

Coffee Lake H Platform

Design Guide

December 2020

Revision 2.3

Intel Confidential



You may not use or facilitate the use of this document in connection with any infringement or other legal analysis concerning Intel products described herein. You agree to grant Intel a non-exclusive, royalty-free license to any patent claim thereafter drafted which includes subject matter disclosed herein.

No license (express or implied, by estoppel or otherwise) to any intellectual property rights is granted by this document.

Intel technologies' features and benefits depend on system configuration and may require enabled hardware, software or service activation. Performance varies depending on system configuration. **No computer system can be absolutely secure.** Check with your system manufacturer or retailer or learn more at intel.com.

Intel technologies may require enabled hardware, specific software, or services activation. Check with your system manufacturer or retailer.

The products described may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Intel disclaims all express and implied warranties, including without limitation, the implied warranties of merchantability, fitness for a particular purpose, and non-infringement, as well as any warranty arising from course of performance, course of dealing, or usage in trade.

All information provided here is subject to change without notice. Contact your Intel representative to obtain the latest Intel product specifications and roadmaps

Copies of documents which have an order number and are referenced in this document may be obtained by calling 1-800-548-4725 or visit www.intel.com/design/literature.htm.

Intel, Centrino, vPro, Core, Thunderbolt, Ultrabook and the Intel logo are trademarks of Intel Corporation in the U.S. and other countries.

*Other names and brands may be claimed as the property of others.

Copyright © 2017-2020, Intel Corporation



Contents

1	Introduction	35
1.1	Terminology	37
1.2	Reference Documents	37
2	Stack-Up and PCB Considerations	38
2.1	Printed Circuit Board Considerations	38
2.2	Generalized 8-Layer Motherboard Example	44
2.3	Generalized 10-Layer Motherboard Example	45
2.4	Single-Ended and Differential-Impedance Transmission Line Specifications.....	48
2.4.1	Breakout Geometries	48
2.4.2	Routing Geometries	48
2.5	Low Halogen Flame Retardant Stack-Up Considerations	52
2.5.1	Choosing a Low Halogen Material.....	53
2.5.2	Electrical Limits of Low Halogen Material Properties.....	53
2.6	Reference Planes.....	54
2.7	Type 4 PCB Vias.....	54
2.7.1	Plated Through Hole, Buried Via, and Microvia Dimensions	54
2.7.2	Staggered versus Stacked Microvias	55
2.7.3	Buried Via to Microvia Keep-Out	55
2.8	Backward and Forward Coupling Coefficient Calculation	56
2.9	Minimizing the Effect of Fiber Weave.....	58
2.9.1	Overview of Fiber Weave	58
2.9.2	Fiber Weave Effect versus Transfer Rate and Trace Length.....	61
2.9.3	Specific Routing Configurations	61
2.9.4	Offset Routing.....	61
2.9.5	Zig-Zag or Slanted Routing.....	62
2.9.6	Image Rotation	63
2.9.7	Using Alternate PCB Materials	64
2.10	Flexible Printed Circuit Consideration	64
2.11	Coffee Lake Client Signal Integrity Tool Suite	64
3	General Differential Design Guidelines.....	68
3.1	General Differential Stackup Guidelines	68
3.1.1	Stackup and Layer Utilization Guidelines.....	68
3.2	General Differential Routing Guidelines.....	70
3.2.1	Breakout Example and Guidelines.....	70
3.2.2	Differential I/O Routing Scheme Guidelines.....	71
3.3	General Differential Optimization Guidelines	75
3.3.1	Via Placement and Via Usage Optimization.....	75
3.3.2	Bend Optimization Guidelines.....	78
3.3.3	Component Footprint Optimization Guidelines	79
3.3.4	General Routing Guidelines	79
3.4	General Differential Length Matching Guidelines	80
3.4.1	Length Matching and Length Formulas	80
3.5	General Differential Compensation and Voltage Reference Guidelines	83
3.5.1	RCOMP Signal Guidelines	83
3.5.2	Reference Planes.....	83
3.6	General Docking Connector Recommendations for Differential Interfaces	89
3.7	RCOMP	90
4	System Memory Interface Design Guidelines	91



4.1	CFL-H DDR4 ECC SO-DIMM 2DPC Guidelines	94
4.1.1	Stub Reduction and Alternative Pin Map	100
4.2	CFL-H DDR4 SO-DIMM 2DPC Guidelines	100
4.3	CFL-H DDR4 SO-DIMM 1DPC Guidelines	103
4.4	CFL H DDR4 ECC SO-DIMM 1DPC guidelines	108
4.5	CFL-H DDR4 1R x16 Memory Down Guidelines	110
4.6	CFL-H DDR4 2R x8 Memory Down Guidelines	116
4.7	CFL-H DDR4 Mixed SODIMM and Memory Down x16 Daisy-Chain Topology	122
4.8	CFL-H DDR4 Mixed SODIMM and Memory Down x8 Daisy-Chain Topology	124
4.9	CFL-H LPDDR3 x32 Memory Down	126
4.10	CFL-H System Memory ODT Signal Connectivity Details	130
4.11	Memory Data Mask (DM) Signals Connectivity Details	130
4.12	.CFL H System Memory Via Placement and Pad Optimization Guidelines	130
4.12.1	Via Placement at CPU Side	130
4.12.2	Via Placement at SO-DIMM and DRAM Device Side	131
4.13	CFL H System Memory Reference Voltage (VREF) Guidelines	132
4.14	CFL-H DDR Power Delivery - Memory side	135
4.14.1	CFL-H DDR4 SODIMM Decoupling	136
4.14.2	CFL-H DDR4 Memory Down Decoupling	137
4.14.3	CFL-H LPDDR3 x32 Memory Down Decoupling	138
5	DisplayPort* Design Guidelines.....	142
5.1	Introduction	142
5.1.1	DisplayPort* Link Bit Rates	142
5.1.2	DisplayPort* Main Link Buffer Type	143
5.1.3	Reference Documents	143
5.2	DisplayPort* Signal Descriptions	143
5.2.1	Signal Groups	143
5.3	DisplayPort* Topology Guidelines	144
5.3.1	Optimizations	144
5.3.2	DisplayPort* Main Link Motherboard Topologies	145
5.3.3	Display Port* Main Link on Dock Topology with Redriver Topologies	146
5.3.4	Display Port* Main Link Internal Cable Topology	148
5.3.5	DisplayPort* Auxiliary Channel Topologies	149
5.4	DisplayPort* General Considerations and Optimization	151
5.4.1	DisplayPort* HPD General Considerations and Optimization	151
5.4.2	DP_PWR Pin Back Drive Protection	152
5.4.3	DisplayPort* Main Link Differential-Pair Width and Spacing	153
5.4.4	DisplayPort* Auxiliary Channel (AUX CH) General Design Considerations and Optimization	153
5.5	DisplayPort* Length Matching Guidelines	155
5.6	Digital Display Interface Disabling and Termination Guidelines	155
5.7	Display Compensation Guidelines	155
6	Embedded DisplayPort* (eDP*) Design Guidelines	156
6.1	Signal Descriptions	156
6.2	Topology Guidelines	156
6.3	Optimizations	157
6.3.1	Coffee Lake Processor Graphics Embedded DisplayPort* Main Link Topology for HBR and HBR2	158
6.3.2	Embedded DisplayPort* to VGA Main Link Topology	159
6.3.3	Embedded DisplayPort* Hot-Plug Detect Implementation	160
6.4	Length Matching Guidelines	161
6.5	Digital Display Interface Compensation Guidelines	161
6.5.1	Compensation Signal Routing Guidelines	162
6.5.2	Disabling and Termination Guidelines	162



7	High-Definition Multimedia Interface* (HDMI*) Design Guidelines	163
7.1	Overview	163
7.2	Signal Description	166
7.3	HDMI 1.4* Topology Guidelines.....	166
7.3.1	Differential-Pair Width and Spacing.....	166
7.3.2	Optimizations	166
7.3.3	HDMI 1.4* Main Link Cost-reduced Level Shifter Topology	167
7.3.4	HDMI 1.4* Main Link Active Level Shifter Topology	168
7.3.5	HDMI 1.4* Docking Active Level Shifter Docking Topology	170
7.3.6	HDMI 1.4* Internal Cabled Solution	171
7.3.7	HDMI 1.4* (DDC) Signals Design Guidelines	172
7.3.8	HDMI 1.4* HPD Implementation	175
7.4	HDMI* 2.0 Topology Guidelines.....	177
7.4.1	HDMI 2.0* HPD Implementation	178
7.5	Digital Display Interface Disabling and Termination Guidelines.....	179
7.6	Display Compensation Guidelines	179
8	Processor - PCI Express* Design Guidelines	180
8.1	Introduction	180
8.1.1	Compliance Documents	180
8.2	Signal Description	180
8.3	Topologies Guidelines	180
8.4	General Routing Guidelines	183
8.4.1	Reference Planes.....	183
8.4.2	Lane to Controller Allocation	183
8.5	Slot Reset Implementation	187
8.6	Debug Guidelines	188
8.6.1	Probe Points for Testing Soldered Down PCI Express* Devices	188
8.6.2	Desktop Form Factor Passive Components and Connectors.....	189
8.6.3	AIO Form Factor Passive Components and Connectors.....	190
8.6.4	Passive Components	191
8.7	Compensation Guidelines	192
9	Direct Media Interface Design Guidelines	194
9.1	Introduction	194
9.1.1	Compliance Specification	194
9.2	Signal Descriptions	194
9.3	Topology Guidelines.....	194
9.3.1	Differential-Pair Width and Spacing.....	194
9.3.2	DMI 2-Via Topology	194
9.4	Configuration.....	195
9.4.1	Lane Reversal and Polarity Inversion Support	195
9.5	Compensation Guidelines	196
10	Hybrid Graphics	197
10.1	Introduction	197
11	Thunderbolt™ Design Guidelines	198
11.1	Supported Thunderbolt™ Configuration Options.....	199
11.2	Thunderbolt™ Port Power Requirements	200
11.2.1	Host Source Requirements	200
11.3	Power Delivery.....	200
11.3.1	Thunderbolt™ Power Provider VBUS Electrical Requirements	200
11.3.2	Thunderbolt™ VCONN Source Electrical Requirements	201
11.3.3	Thunderbolt™ BIOS	201
11.3.4	Reference Documents	203



11.3.5	Compliance Specification	203
11.3.6	Thunderbolt™ Signal Descriptions	203
11.4	Thunderbolt™ Topology Guidelines.....	204
11.4.1	Motherboard Down Topology	204
11.4.2	DisplayPort* to Thunderbolt™ Topology	205
11.4.3	Add-In Card Topology	205
11.4.4	Thunderbolt™ Connector Guideline.....	206
11.5	Thunderbolt™ Length Matching Guidelines	206
11.6	Thunderbolt™ Stack-up Guidelines.....	208
11.6.1	Stack-up and Layer Utilization Guidelines.....	208
11.6.2	Thunderbolt™ Insertion Loss Spec	208
11.7	Thunderbolt™ Optimization Guidelines.....	208
11.7.1	TBT Lane Routing and Component Placement	208
11.7.2	Via Placement and Via Pad Optimization.....	208
11.8	Thunderbolt™ Debug Guidelines	208
11.8.1	PCIe* and DisplayPort* Configuration	208
11.8.2	NVM Configuration	209
11.9	Thunderbolt™ Additional Guidelines.....	209
11.9.1	Crystal Design Requirement	209
11.9.2	NVM.....	209
11.9.3	Thunderbolt Native PCIe* Mode	209
11.9.4	Modern Standby and Runtime D3 Support.....	209
11.9.5	Hardware Changes to Support TBT PCIe* RTD3	210
12	Clock and Low Speed I/Os	211
12.1	Platform Clock Design Guidelines	211
12.1.1	Platform Clock Interface Details	211
12.1.2	Platform Clock Signal Descriptions	212
12.2	Platform Clock Guidelines.....	212
12.2.1	ITP_XDP Differential Clock Routing Guidelines.....	212
12.2.2	CPU Differential Clock Routing Guidelines	213
12.2.3	PCIe* Differential Clock Routing Guidelines to Add-in Card	214
12.2.4	PCIe* Differential Clock to Down Device Routing Guidelines.....	215
12.2.5	Single-Ended LPC Clock Routing Guidelines	216
12.3	Platform Clock Associated Signal Guidelines	216
12.3.1	SRC Clock Request Routing Guidelines.....	216
12.3.2	24 MHz Input Clock Routing Guidelines	217
12.3.3	XCLK_BIASREF Guidelines.....	220
13	Real Time Clock (RTC) Design Guidelines	222
13.1	Real Time Clock (RTC) Design Guidelines	222
13.1.1	RTC Signal Description	222
13.1.2	RTC Topology Guideline	222
13.1.3	RTC External RTCRST# Circuit	225
13.1.4	RTC External SRTCST# Circuit	226
14	Asynchronous and Sideband Signals Design Guidelines.....	227
14.1	Signal Descriptions	227
14.1.1	Signal Groups	227
14.2	Topology Guidelines	228
14.2.1	PROCHOT# Topology	229
14.2.2	CATERR# Topology	230
14.2.3	PROCPWRGD Topology	231
14.2.4	VCCST_PWRGOOD Topology	231
14.2.5	THERMTRIP# Topology	232
14.2.6	RESET# (PLTRST#) Topology	233



14.2.7	Platform Environmental Control Interface (PECI) Topology	233
14.2.8	BPM#[3:0] Topology.....	235
14.2.9	PM_SYNC Topology.....	235
14.2.10	PM_DOWN Topology	236
14.2.11	PROC_TRIGIN Topology (PCH to Processor_TRIGIN)	236
14.2.12	PROC_TRIGOUT Topology (Processor to PCH_TRIGIN)	237
14.2.13	SVID Topology	237
14.2.14	COMP Signals	238
14.3	ESD Protection for Asynchronous Signals.....	238
15	Flexible I/O	239
15.1	Overview	239
15.2	Flexible I/O Implementation	239
15.2.1	Cannon Lake HPCH-H	239
16	PCH PCI Express* Interface Design Guidelines	241
16.1	PCH PCI Express* Interface Configuration Details	241
16.2	Intel® Rapid Storage Technology (Intel® RST) for PCH PCIe* Storage	242
16.3	PCH PCI Express* Signal Descriptions	242
16.4	PCH PCI Express* Routing Guidelines.....	243
16.4.1	PCH PCI Express* Device Down Guidelines	243
16.4.2	PCH PCI Express* Add-In Card Connector Guidelines	244
16.4.3	PCH PCI Express* with Internal Cable Guidelines	245
16.4.4	PCH PCI Express* M.2 Socket Module Guidelines	246
16.4.5	PCH PCI Express* Impedance Compensation Guidelines	246
16.4.6	PCH PCI Express* Lane Polarity Inversion	247
16.4.7	PCH PCI Express* Controller Lane Reversal.....	247
17	SATA Interface Guidelines	250
17.1	Overview	250
17.2	SATA Signal Description	250
17.2.1	SATA Signal Groups.....	250
17.2.2	SATA Signal Considerations	250
17.3	SATA General Guidelines	251
17.3.1	General SATA Routing Guidelines.....	251
17.3.2	SATA Test Points and Probing	252
17.3.3	SATA Additional Guidelines	252
17.3.4	SATA Disabling and Termination Guidelines.....	254
17.4	SATA Topologies and Guidelines	254
17.4.1	mSATA/Direct Connect.....	254
17.4.2	SATA Direct Connect with Internal Cable Topology	256
17.4.3	Internal SATA (Cable Connect) Topology	259
17.5	Compliance Requirements	259
18	Universal Serial Bus USB 3.1 Design Guidelines	260
18.1	USB 3.1 Signal Descriptions.....	260
18.1.1	Signal Groups	260
18.1.2	Overcurrent Protection	260
18.1.3	USB 3.1 Topology Guidelines	261
18.1.4	USB 3.1 Specific Topology Guidelines	267
18.1.5	USB 3.1 General Guidelines	270
18.1.6	USB 3.1 Optimization Guidelines	271
18.1.7	USB Connector/Receptacle Recommendations	271
18.1.8	USB 3.1 Disabling and Termination Guidelines.....	272
19	Universal Serial Bus 2.0 Design Guidelines	274
19.1	USB 2.0 Signal Groups.....	274



19.2	USB2_COMP Topology	274
19.3	USB2_COMP Routing Guidelines.....	275
19.4	USB2_COMP to Other Interfaces	275
19.5	Overcurrent Protection	276
19.5.1	Overcurrent Pin Mapping.....	277
19.6	Integrated Bluetooth* and USB 2.0 Design Considerations	277
19.7	USB 2.0 Topology Guidelines	277
19.7.1	Back Panel/External Topology.....	277
19.7.2	On-The-Go Topology	278
19.7.3	USB 2.0 with M.2 Topology	279
19.7.4	USB 2.0 Flex/Internal Cable Topology	280
19.7.5	USB 2.0 Device Down Topology	283
19.7.6	USB 2.0 External / Back Panel with Power Switch / BC1.2 Charger Module / MUX Topology	284
19.7.7	USB 2.0 Docking Topology	285
19.7.8	USB 2.0 Detachable Docking Topology.....	286
19.7.9	USB Connector Recommendations.....	288
19.7.10	Daughter Card	289
19.7.11	USB 2.0 Stack-up Guidelines	290
19.7.12	Stack-up and Layer Utilization Guidelines	290
19.7.13	USB 2.0 Configuration, Connectivity, Block Diagram	290
19.7.14	Port Power Delivery.....	290
19.7.15	USB 2.0 Length Matching Guidelines	291
19.7.16	EMI and ESD Protection	291
19.7.17	USB 2.0 Disabling and Termination Guidelines	291
20	USB Type-C	292
20.1	USB Type-C Platform- Specific Important Information.....	295
20.2	USB Type-C Signal Group and Descriptions	295
20.3	USB Type-C Topology Guidelines	296
20.3.1	USB 2.0 Guidelines	296
20.3.2	USB 3.1 Guidelines	300
20.3.3	USB Type-C with DP* as Alternate Mode	309
20.4	USB Type-C Power Delivery.....	314
20.4.1	USB Type-C VBUS and VCONN Control	314
20.4.2	USB Type-C VBUS Options	315
20.5	Overcurrent Protection	317
20.6	Layout Optimization	318
20.6.1	CC Pins Layout	318
20.7	Type-C Connector Footprint Voiding Guideline.....	318
20.8	USB Type-C Component Selection Guidelines.....	319
20.9	Reference Documents.....	319
21	PCH Signal Glitch Free Implementation Requirements	321
21.1	Overview	321
21.2	Implementation Details	321
22	MIPI SoundWire* Interface Design Guidelines.....	323
22.1	SoundWire Platform Specific Important Information.....	323
22.2	SoundWire Signal Description	323
22.3	SoundWire Topology Guidelines	323
22.3.1	Large System Topology - Single Load Configuration Using Cables	324
22.3.2	Large System Topology - Single Load Configuration with Device Down	324
22.4	Additional Guidelines	325
22.4.1	Adjusting Drive Impedance for Down Devices	325
23	I²C* Interface Design Guidelines	327



23.1	I ² C Platform Specific Important Information	327
23.1.1	I ² C Signal Descriptions.....	327
23.1.2	I2C Topology Guidelines	327
23.1.3	Tools	331
24	Universal Asynchronous Receiver Transmitter (UART) Interface Design Guidelines	332
24.1	UART Platform Specific Important Information.....	332
24.1.1	UART Signal Descriptions	332
24.1.2	UART Topology Guidelines	332
24.1.3	Tools	333
25	Generic Serial Peripheral Interface (GSPI)	334
25.1	GSPI Platform- Specific Important Information	334
25.1.1	GSPI Signal Descriptions	334
25.1.2	GSPI Topology Guidelines	334
25.1.3	Debug Guidelines/Recommendations.....	335
25.1.4	Tools	335
26	Enhanced Serial Peripheral Interface (eSPI)	336
26.1	Introduction	336
26.2	Topology and Guidelines.....	336
26.2.1	Topology	336
26.2.2	Routing Guidelines	337
27	SMBus 2.0/SMLink Interface Design Guidelines	339
27.1	SMBus 2.0/SMLink Platform Specific Important Information	339
27.1.1	SMBus 2.0/SMLink Signal Descriptions	339
27.1.2	SMBus 2.0/SMLink Topology Guidelines	340
27.1.3	Detailed Routing Requirements	340
27.1.4	SMBus and SMLink Connectivity Recommendation	341
27.1.5	Additional Guidelines	344
27.1.6	Compliance Requirements	346
27.1.7	Tools	346
28	Secure Digital Card with Extended Capacity (SDXC) Interface Design Guidelines ...	347
28.1	SDXC Signal Descriptions	347
28.1.1	SDXC Topology Guideline	347
29	Low Pin Count (LPC) Interface Design Guidelines	349
29.1	Overview	349
29.2	LPC Signal Description	349
29.2.1	LPC Topology Guidelines.....	350
29.2.2	LPC DATA 3 Load Daisy Chain Topology Guidelines	350
29.2.3	LPC CLK Single Load Topology	351
29.2.4	Disable Guidelines	351
29.2.5	General Guidelines for Length Matching Requirements.....	352
30	Serial Peripheral Interface (SPI0) Flash Design Guidelines	353
30.1	Overview	353
30.2	Serial Peripheral Interface (SPI0) Topology Guidelines.....	354
30.2.1	SPI0 2 Load Topology Guidelines	355
30.2.2	SPI0 2 Load with EC Flash sharing Topology	356
30.2.3	SPI0 3 Load Topology Guidelines	356
30.2.4	SPI0 3 Load with EC Flash Sharing Topology	357
31	Serial Peripheral Interface (SPI1) Touch Design Guidelines	360
31.1	SPI1 Touch Platform Specific Important Information	360
31.2	SPI1 Touch Signal Descriptions	360



31.3	SPI1 Touch Topology Guidelines	360
31.3.1	SPI1 Single Load Touch Topology.....	361
31.3.2	SPI1 Touch Length Matching Requirement.....	361
32	Legacy Audio Interface Design Guidelines.....	362
32.1	Legacy Audio Interface Platform Specific Important Information.....	362
32.1.1	Legacy Audio Interface - Signal Description	362
32.1.2	Intel High Definition Audio (Intel HD Audio) and DMIC Topology Guidelines ..	363
32.1.3	Integrated CODEC for Intel Display Audio.....	366
32.1.4	Disabling and Termination Guidelines for the Intel High Definition Audio Interface	367
32.1.5	I ² S* Device Connection Topology.....	367
33	Intel® Management Engine (Intel® ME)	369
33.1	Acronyms	369
33.2	Preface.....	369
33.3	Reference Documents.....	370
33.4	Introduction	370
33.5	Intel® ME Signal Descriptions	370
33.5.1	Intel® ME to Embedded Controller Interface Signals	371
33.6	Optimization Guidelines	371
33.6.1	Intel® ME Guidelines	371
33.6.2	For Intel® AMT support, Intel® ME Wake on LAN is a requirement.....	374
33.6.3	WLAN Considerations with Intel® Active Management (Intel® AMT) Support.	374
33.6.4	SPI Flash Descriptor Security Override.....	374
33.7	Intel® APS	374
33.8	Intel® ME Firmware behavior in Coffee Lake.....	379
33.9	Schematics Design Checklists	379
33.9.1	Overview	379
33.9.2	Intel® ME Checklists	380
34	Intel® Integrated Sensor Solution	383
34.1	Acronyms	383
34.2	Reference Documents.....	383
34.3	Introduction	384
34.4	Overview	384
34.5	Sensors.....	384
34.6	Sensors Extensibility Options.....	385
34.6.1	Baseline	385
34.6.2	BOM Flexibility	386
34.6.3	BOM Innovation.....	386
34.7	Design Integration	386
34.7.1	Electrical Design	386
34.7.2	Layout and Assembly	389
34.7.3	Form Factor Considerations	389
34.7.4	PCB and Cable Routing	402
34.7.5	Sensor Problem Areas	403
34.8	System Debug.....	406
34.8.1	Firmware Debug Hooks.....	407
34.8.2	Sensors Debug Hooks	407
34.9	Intel® ISS Checklists.....	413
34.9.1	Schematics Design Checklists	414
34.9.2	PCB Layout and System Design Checklists.....	417
35	Discrete Trusted Platform Module (TPM) Design Guidelines.....	423
35.1	Signal Description.....	424
35.1.1	Signal Groups	424



36	Platform Reset Considerations	425
36.1	Signal Description	425
36.1.1	Signal Groups	425
36.2	Additional Guidelines	426
36.2.1	SYS_RESET# Usage Model	426
36.2.2	SLP_A# Usage Model	426
36.2.3	SLP_S0# Usage Model	426
36.2.4	SLP_S3# Usage Model	426
36.2.5	SLP_S4# Usage Model	426
36.2.6	SLP_S5# Usage Model	426
36.2.7	SLP_LAN# Usage Model	427
36.2.8	SLP_WLAN# Usage Model	427
36.2.9	SLP_SUS# Usage Model	427
36.2.10	SUSWARN# / SUSPWRDNACK Usage Model	427
36.2.11	SUSACK# Usage Model	427
36.2.12	PWRBTN# Usage Model	427
36.2.13	PLTRST# Usage Model	428
36.2.14	SUSCLK Usage Model	428
36.2.15	RSMRST# Generation	428
36.2.16	DSW_PWROK Generation	428
36.2.17	PCH_PWROK Generation	428
36.2.18	SYS_PWROK Generation	428
36.2.19	Legacy Requirements	429
36.2.20	Additional Power Sequencing Considerations	429
37	Interrupt Interface Design Guidelines	430
37.1	Signal Description	430
37.2	Additional Guidelines	430
37.2.1	PIRQ Routing Example	430
38	Critical Low Speed Signals Design Guidelines	432
38.1	Signal Description	432
38.1.1	Signals Group	432
38.2	Additional Guidelines	433
39	M.2 Module	434
39.1	Overview	434
39.1.1	Reference Specifications	434
39.2	Supported M.2 Features	434
39.2.1	Connector Keys	434
39.2.2	Module Stand-off	434
39.2.3	Schematics Connector Symbol - Design Considerations	435
39.3	Design Guidelines for M.2 Interfaces	437
39.3.1	PCI Express* Interface	437
39.3.2	SATA Interface	439
39.3.3	USB 3.0 Interface (USB3.1 Gen1)	440
39.3.4	USB 2.0 Interface	440
39.3.5	SMBus and I2C Topology Guidelines	440
39.3.6	UART and SPI Topology Guidelines	440
40	Front Facing HD/FHD Webcam Design Guidelines	441
40.1	Design Considerations	441
41	LAN Design Considerations and Guidelines	444
42	Wireless Connectivity Integration (CNVi) Design Considerations	445
42.1	Connectivity Integration (CNVi)	445



42.2	Platform High-level Description.....	445
42.2.1	System-on-Chip (SoC)	446
42.2.2	Platform Crystal.....	446
42.2.3	WWAN Co-existence.....	446
42.2.4	Platform VRs	447
42.2.5	CNVi Related Straps	447
42.2.6	Connectivity.....	447
42.2.7	Connectivity Antennas	447
42.3	CNVi Form Factors	447
42.3.1	RF Companion M.2 (2230)	447
42.3.2	Soldered Down M.2 (SD-1216)	455
42.4	Platform Considerations.....	463
42.4.1	Selecting Connectivity Solution	463
42.4.2	CNVi Reference Clock	464
42.4.3	SoC RCOMP Pin Connection	467
42.4.4	RF-Kill and LED Support.....	467
42.4.5	CLINK Support	468
42.4.6	CNVi Power Supply Connections.....	468
42.4.7	Electrical Specifications for CNVi 1.8V Signals	470
42.4.8	CNVi Power Rails Table	473
42.4.9	CNVi Power-up Sequence.....	473
42.4.10	CNVi Platform Connections	475
42.4.11	USB 2.0 Port for Bluetooth	476
42.5	CNVio Bus	476
42.5.1	Routing Guidelines for CNVio	476
42.5.2	Tools for Analysis.....	479
42.5.3	Tools for Debug	479
42.5.4	CNVio Probing	479
42.5.5	Routing Guidelines for BRI/RGI	480
42.5.6	Modem Coexistence 3-way UART Connection	483
42.5.7	SoC Termination Requirements.....	484
42.5.8	RF Companion Specifications	484
42.6	Standard M.2 Connectivity Design Considerations	484
42.6.1	Standard (Discrete) Connectivity Guidelines	484
42.6.2	PCIe Host Interface Errata	486
43	Wireless Modules and Antenna Design Guidelines	489
43.1	Antenna Design Guidelines	489
43.1.1	Antenna Integration	489
43.1.2	Antenna Performance	489
43.1.3	Antenna Placement	492
43.1.4	RF System-Level Integration Recommendations	496
44	Platform Telecom Design Guidelines	500
44.1	Safety Rules	500
44.2	EMC Rules and Regulations	500
44.3	Telecom Safety Considerations	500
44.4	Configuration	502
44.4.1	Isolation	502
44.4.2	Surge.....	502
44.4.3	Example of Wrong Implementation	503
44.5	Additional Guidelines	504
45	Platform Power Sequencing Specification	505
45.1	PCH_PWROK, SYS_PWROK and Other PWRGD Signal Generation.....	505
45.2	Sequencing Interface Signals List and Power Rails	506



45.3	Power States	510
45.4	Power Sequencing Timing Diagrams—Legacy Signals	511
45.4.1	Power Sequencing Timing Requirements.....	520
45.5	Additional Power Optimizations with Respect to VCCST Rail in S3	527
45.6	Rail-to-Rail Power Sequencing Requirements.....	527
45.6.1	Rail-to-Rail Sequencing For Various Supplies.....	527
45.6.2	RSMRST#/DSW_PWROK Special Considerations	530
45.6.3	Surprise Power Down Sequencing Considerations	531
45.6.4	eSPI Considerations for Sequencing	533
45.6.5	Virtual wire SUSWARN deassertion delay during global reset	533
46	Platform Debug and Test Hooks.....	534
46.1	Platform Debug Port Options.....	534
46.1.1	Primary Debug Port Debug Port Routing Guidelines	537
46.1.2	Secondary Debug Port Routing Guidelines.....	557
46.1.3	Intel® DCI Implementation.....	564
46.1.4	eXtended Debug Port (XDP) Mechanical Specifications	570
46.1.5	Chassis Mount Connector (CMC) Mechanical Specifications	572
46.1.6	Additional Debug Port PCB Layout Guidelines	579
46.1.7	Additional Routing Guidelines to support Intel® Silicon View Technology (Intel® SVT) based DFM HVM Test Solution	582
46.1.8	Depopulation Guidelines for Debug Port.....	583
47	Platform Thermal Management Design Guidelines	584
47.1	Platform Thermal Management Signal Descriptions	584
47.1.1	Signal Groups	584
47.2	Platform Thermal Management Configuration, Connectivity, Block Diagram	584
48	Acoustic Noise Mitigation	586
48.1	Introduction	586
48.2	Noise Mitigation	587
48.2.1	Mechanical Mitigation.....	587
48.2.2	Architectural Mitigation	588
49	Electromagnetic Compatibility	592
49.1	General Considerations	592
49.1.1	Ground Ring/ PTH	592
49.1.2	Power Plane Decoupling	593
49.1.3	Connector Decoupling	594
49.1.4	Crossing Split planes	595
49.1.5	Reference Discontinuity.....	596
49.2	Power Supply.....	596
49.2.1	Voltage Regulator.....	596
49.2.2	AC Jack.....	597
49.3	Critical Signals	598
49.3.1	Audio.....	598
49.3.2	LPC	598
49.3.3	Integrated Touch (SPI)	598
49.3.4	Crystal (Xtal) RF Immunity	600
49.3.5	EMC Sensitive Nets.....	601
49.4	Connectors	602
49.4.1	General Guidelines	602
49.4.2	USB.....	602
49.4.3	Audio Jack.....	605
49.5	Cables/ Shielding	605
49.5.1	Shielded FFC	605
49.6	PCB CMC Technology	606



49.7	Components Selection	607
49.7.1	Type C EMI and ESD Components	609
50	Processor and PCH Power Integrity Recommendations	611
50.1	Processor Decoupling and Layout Recommendations.....	611
50.1.1	Coffee Lake H Processor Layout Recommendation	611
50.1.2	Coffee Lake Decoupling Requirement.....	613
50.1.3	VCCST PLL Jitter Recommendation	616
50.1.4	Impedance Spectrum Tool (IST/IFDIM) Testing Requirements and Recommendations	617
50.2	PCH Decoupling / Filter and Sense Point Recommendations	619
50.2.1	Power Plane Decoupling Recommendations	619
50.2.2	VR Sense Requirements for PCH Rails.....	622
50.3	Loop Inductance Reduction Decoupling	622
50.4	Power Plane Isolation	623
50.4.1	CNL PCH-H Power Rail Isolation and Routing Recommendations	624
50.5	Coffee Lake H Land Pattern Recommendations.....	629
51	Power Delivery	633
51.1	Power Maps	633
51.1.1	Power Map Tool	633
51.1.2	Load Switch Sizing	633
51.1.3	Trade-offs - Volume vs. Premium Power Maps	634
51.1.4	VccSTG Rail Discharge Requirements.....	635
51.2	Processor Power Delivery Guidelines.....	635
51.2.1	General Processor Power Delivery Considerations	635
51.2.2	Testing and Validation	636
51.2.3	Audible Noise Reduction	637
51.2.4	Vcc_SENSE/Vss_SENSE Package Sensing	638
51.3	IMVP8 Voltage and Current Requirements- H-Line	640
51.4	Voltage Regulator Requirements	643
51.5	AC Adapter Considerations	646
51.5.1	Power Budgeting for AC Adapter	646
51.5.2	Transient Power Requirement for Turbo	646
51.5.3	Sustained Power Requirement at Dead Battery Level	646
51.5.4	Psys and Other Considerations for Using Smaller AC Adapter	647
51.5.5	Protection Mechanisms	648
51.6	Battery Charging System	648
51.6.1	Hybrid Power Boost (HPB) Battery Charger.....	648
51.6.2	Narrow VDC (NVDC) Battery Charger	649
51.6.3	Benefits and Trade-Offs	650
51.6.4	Chargers Supporting 5V-20V USB Charging	650
51.7	Platform Power Monitoring And Control (PSYS)	652
51.7.1	Benefits.....	652
51.7.2	Theory Of Operation.....	653
51.7.3	Hardware Ingredients	653
51.7.4	Software/Firmware Ingredients.....	656
51.7.5	Configuration	657
51.7.6	Implementation of PSYS	657
51.8	Battery and Fuel Gauging System	658
51.8.1	Dynamic Battery Power Technology.....	659
51.8.2	Fuel Gauging	660
51.8.3	Battery Pack Size and Configuration	662
51.9	Dynamic Fast Charging Technology-DFCT.....	663
52	Flexible Instrumented Platform (FIP) Design.....	665



52.1	Background	665
52.2	Overview		667
52.3	FIP Design Details		670
52.3.1	FIP Details and Steps.....		670
52.4	DuPont Header Connector		676
52.5	General Guidance for the FIP Solution		677
52.6	Routing Overview for Current Sense Resistor Calibration.....		679
52.7	General PCB Via/Trace Calculator Routing Guidelines.....		680
52.8	Summary		680
53	Designing for Power Optimized S0ix Platforms (Connected Standby/Modern Standby)		
681			
53.1	Overview		681
53.1.1	S0 Idle (S0ix) Soc Design References		682
54	Compatibility with Other Platforms.....		685
54.1	Compatibility with Legacy Platforms	685

Figures

1-1	Coffee Lake H Platform Block Diagram		35
2-1	Single-Ended Microstrip Diagram.....		38
2-2	Differential-Microstrip Diagram		38
2-3	Single-Ended Dual-Stripline Diagram		41
2-4	Differential Dual-Stripline Diagram		41
2-5	Single-Ended Stripline Diagram.....		41
2-6	Differential Stripline Diagram.....		42
2-7	CFL H Dual-Stripline 8-Layer Type 3 PCB Stack-Up		43
2-8	CFL H 10 Layer Type 3 PCB Stack-Up		44
2-9	CFL H 10-Layer Type 4 PCB Stack-Up 2-x-2+ (L5, L6 is 1 oz. copper)		45
2-10	CFL H 10-Layer Type 4 PCB Stack-Up 1-x-1.....		46
2-11	Staggered vs. Stacked Microvias		54
2-12	Type 4 PCB PTH to Microvia Keep Out.....		55
2-13	Backward Coupling Coefficient		56
2-14	Forward Coupling Coefficient		56
2-15	Single Ended Kb Diagram.....		56
2-16	Differential Kb Diagram		57
2-17	Common Glass Cloths Used in PCB Manufacture.....		58
2-18	Inhomogeneous Nature of a PCB as Shown in this Cross-Section		58
2-19	Effect of Skew on Differential and Common Mode Signals		59
2-20	Cross-Section of PCB Indicating Effect of PCB Fiber Weave		59
2-21	An Example of Offset Routing		61
2-22	An Example of Zig-Zag Routing.....		61
2-23	An Example of Slanted Routing		62
2-24	An Example of a PCB Cut Such That Its Edges are Rotated Relative to the Fiber Weave Pattern		63
2-25	Snapshot of Electrical Channel Simulator (ECS).....		64
2-26	Snapshot of freqMasterEx Toolbox.....		65
2-27	Snapshot of TlineCalc		66
3-1	Tx-over-Tx, Rx-over-Rx, and Tx-over-Rx.....		67
3-2	Dual-Stripline Orthogonal Routing Recommendation		67
3-3	Dual-Stripline High Speed Signal Dual Layer Routing Recommendation		68
3-4	Recommended Routing Angle to Reduce Layer-to-Layer Crosstalk		68
3-5	Board Breakout Example.....		69
3-6	Board Breakout Example.....		69
3-7	Differential-Pair Spacing Diagram.....		70



3-8	Symmetrical and Non-Symmetrical Routing Example.....	70
3-9	HSIO Non-interleaved Breakout Guidelines	71
3-10	Non-interleaved versus Interleaved Routing	72
3-11	HSIO Interleaved or Semi-Interleaved Main Routing.....	73
3-12	Differential Routing Guidelines	74
3-13	Via Pair Example	75
3-14	Example - Via Placement 1	75
3-15	Example - Via Placement 2	76
3-16	Board Breakout Example - Via Placement 3.....	76
3-17	Differential Transitional Via Layout.....	77
3-18	Acceptable Bends vs. Tight Bends Example	78
3-19	Maximum Bend Angle	78
3-20	Example - Length Matching.....	80
3-21	Example - Serpantining	80
3-22	Example - Etch Located within a Pad.....	80
3-23	Example - Good Length Matching	81
3-24	Example - Poor Length Matching	81
3-25	Example - Solid Reference Plane Option	84
3-26	Example with Low ESL Stitching Capacitor	85
3-27	Example - Routing over Split Plane	86
3-28	Example - Routing Over Split Plane With Low ESL Stitching Capacitor.....	86
3-29	Example - Routing Over Split Plane and GND Planes are Unable to be Inserted	87
3-30	Example - Routing Over Split Plane and GND Planes are unable to be Inserted With Low ESL Stitching Capacitor	88
3-31	Example Port A Assignment for Docking Connector	89
3-32	RCOMP recommendations	89
4-1	CFL-H DDR4 ECC SO-DIMM 2DPC Block Diagram	94
4-2	CFL-H DDR4 ECC SO-DIMM 2DPC Block Placement.....	94
4-3	CFL-H DDR4 ECC SO-DIMM 2DPC Signals Topology.....	95
4-4	Stubs on 2 DIMMs Per Channel Configurations.....	99
4-5	CFL-H DDR4 SO-DIMM 2DPC Block Diagram.....	100
4-6	CFL-H DDR4 SO-DIMM 2DPC Block Placement	101
4-7	CFL-H DDR4 SO-DIMM 2DPC Signals Topology	101
4-8	CFL-H DDR4 SO-DIMM 1DPC Block Diagram.....	103
4-9	CFL-H DDR4 SO-DIMM 1DPC Block Placement	103
4-10	CFL-H DDR4 1Rx16 Memory Down Placement and Block Diagram	110
4-11	CFL-H DDR4 1Rx16 Memory Down Strobe/Data/RCOMP Signal Topologies	110
4-12	CFL-H DDR4 1Rx16 Memory Down CLK/CTRL/CKE/CMD/Reset Signal Topology	111
4-13	CFL-H DDR4 x8 Memory Down Placement and Block Diagram.....	116
4-14	CFL-H DDR4 x8 Memory Down CLK/CKE/CMD/CTRL/ALERT/Reset Signals Topologies....	117
4-15	CFL-H DDR4 x8 Memory Down DQ/DQS/RCOMP Signals	117
4-16	CFL-H DDR4 x8 Memory Down Placement and Block Diagram.....	124
4-17	CFL-H LPDDR3 x32 Memory Down Placement and Block Diagram.....	126
4-18	CFL-H LPDDR3 x32 Memory Down Strobe/Data/RCOMP Signal Topologies	126
4-19	CFL-H LPDDR3 x32 Memory Down CLK/CKE/CMD Signal Topologies	126
4-20	CFL-H LPDDR3 x32 Memory Down CTRL Signal Topologies	127
4-21	Remove PADs from Layers that Do Not Connect to Trace	130
4-22	CFL-H DDR4 SO-DIMM VREF-CA Overview	132
4-23	CFL-H DDR4 x16 Memory Down VREF-CA Overview	132
4-24	CFL-H DDR4 x8 Memory Down VREF-CA Overview	133
4-25	CFL-H LPDDR3 x32 Memory Down VREF-DQ and VREF-CA Overview	134
4-26	Decoupling Connections at the LPDDR3 Device	137
4-27	Decoupling at the LPDDR3 device	139
4-28	Decoupling at the LPDDR3 Device	140
5-1	DisplayPort* Channels	141



5-2	CFL DisplayPort* Main Link Direct Motherboard Topology	144
5-3	CFL H DisplayPort* Main Link Muxed Port Sharing Topology	144
5-4	CFL H DisplayPort* Docking Topology with Re-driver	145
5-5	CFL H DisplayPort* Main Link Multiplexed Port Sharing on Dock Topology	146
5-6	CFL H DisplayPort* Main Link Internal Cable Topology.....	147
5-7	CFH H DisplayPort* Auxiliary Channel External (Topology A).....	148
5-8	CFH H DisplayPort* Auxiliary Channel Multiplexed Port Sharing on Motherboard (Topology B)	
148		
5-9	CFH H DisplayPort* Auxiliary Channel Docking with Re-driver Aux Sampling (Topology C) ..	
148		
5-10	CFH H DisplayPort* Auxiliary Channel Docking with Re-driver Aux Buffer (Topology D) .	149
5-11	CFL H DisplayPort* Auxiliary Channel Internal Cable	149
5-12	DisplayPort* HPD Passgate Design Recommendation	150
5-13	DisplayPort* DP_PWR pin 20 Back Drive Protection	151
5-14	DisplayPort* Auxiliary Channel Dual Mode Support Protection Circuit	153
6-1	CFL eDP* Main Link Direct Topology	157
6-2	CFL eDP* Auxiliary Channel Topology	158
6-3	CFL eDP* Main Link Direct DP to VGA Topology	158
6-4	CFL eDP* Aux Channel DP to VGA Converter Topology A	159
6-5	Embedded DisplayPort* HPD Signal.....	160
6-6	Embedded DisplayPort* Compensation Signal Routing Topology	160
7-1	HDMI* Overview	162
7-2	HDMI* 2.0 Overview	163
7-3	CFL HDMI 1.4* Main Link Cost-reduced Level Shifter Motherboard Topology	166
7-4	CFL HDMI 1.4* Main Link Active Level shifter Motherboard Topology	167
7-5	CFL H HDMI 1.4* Main Link Active Level shifter Multiplexed Topology	167
7-6	CFL H HDMI 1.4* Main Link Active Level shifter Docking Topology	169
7-7	CFL H HDMI 1.4* Main Link Active Level shifter Docking Multiplexed Topology	169
7-8	CFL HDMI 1.4* Internal Cabled Solution Topology	170
7-9	CFL HDMI 1.4* DDC Graphics Active Level Shifter Docking Topology	172
7-10	CFL HDMI 1.4* DDC Graphics Active Level Shifter Topology	172
7-11	CFL HDMI 1.4* DDC Cost-reduced Level Shifter Design Recommendation	173
7-12	HDMI 1.4* HPD Active Level Shifter Design Recommendation	174
7-13	HDMI 1.4* HPD Cost Reduced Level Shifter Design Recommendation	175
7-14	CFL H LSPCON Main Link Direct MB Topology	176
7-15	CFL H Type 3 HDMI 2.0 DDC Topology	176
7-16	HDMI 2.0* HPD Implementation	177
8-1	CFL H - PCI Express* Device Down Topology	180
8-2	CFL H - PCI Express* Add-In Card Topology	180
8-3	x16 Lanes Port Splitting	182
8-4	Card Presence Detect Pin Connections	183
8-5	x16 Configuration with Flipped Processor	184
8-6	x16 Configuration with Flipped Socket	185
8-7	Board Preparation Example	187
8-8	Processor PCI Express Compensation Signal Routing Topology	192
9-1	DMI 2-Via Topology.....	194
9-2	DMI Lane Reversal Example	195
11-1	CFL DisplayPort Main link Direct Motherboard Topology for TBT	205
11-2	CFL DisplayPort for TBT Aux link Direct topology	205
11-3	Thunderbolt™ Host Reference Design Block Diagram	206
12-1	Clock Integration Distribution Diagram.....	211
12-2	PCH XTAL Input Configuration Diagram	211
12-3	ITP_XDP Differential Clock Topology	213
12-4	CPU Differential Clock Topology	214
12-5	PCIe* Differential Clock to Add-in Card Topology	215



12-6	PCIe* Differential Clock to Down Device Topology.....	216
12-7	SRC Request Signal Topology.....	217
12-8	PCH-H Platform Crystal XTAL_IN/OUT Topology.....	219
12-9	XCLK Bias Reference Topology	221
12-10	XCLK Bias Reference VSS Shield Spacing Recommendations	221
13-1	RTC Crystal Input Topology	223
13-2	Schottky Diode Circuit to Connect RTC External Battery.....	224
13-3	RTCRST#/SRTCRST# External Circuit for PCH RTC.....	225
14-1	Routing Illustration for CATERR# Topology	230
14-2	Routing Illustration for PROCPWDG Topology	231
14-3	Routing Illustration for VCCST_PWRGOOD Topology	231
14-4	Routing Illustration for THERMTRIP# Topology	232
14-5	Routing Illustration for RESET# (PLTRST#) Topology	233
14-6	BPM#[3:0] Topology.....	235
14-7	Routing Illustration for PM_SYNC Topology	235
14-8	Routing Illustration for PM_DOWN Topology.....	236
14-9	Routing Illustration for PROC_TRIGIN Topology	236
14-10	Routing Illustration for PROC_TRIGOUT Topology	237
14-11	Routing Illustration for SVID Topology.....	237
15-1	High Speed I/O (HSIO) Lane Multiplexing in PCH-H.....	239
16-1	Supported PCH PCI Express* Link Configurations.....	241
16-2	PCH PCI Express* Device Down at 2.5, 5, and 8 GT/s Topology	243
16-3	PCH PCI Express* Add-In Card Connector Topology	244
16-4	PCH PCI Express* with Internal Cable Topology	245
16-5	PCH PCIE_RCOMPP and PCIE_RCOMPN Connections	246
16-6	PCH Polarity Inversion on a TX to RX Interconnect	247
16-7	1x4 Configuration PCH PCI Express* Lane Reversal Example	248
16-8	2x1+1x2 Configuration PCH PCI Express* Lane Reversal Example	249
17-1	Zero Power ODD Timing Diagram	253
17-2	Zero Power ODD - Chipset GPIO Implementation Example	253
17-3	Zero Power ODD - Embedded Controller GPIO Implementation Example	254
17-4	mSATA and Direct Connect Topology	255
17-5	SATA Direct Connect with Internal Cable Topology	257
17-6	SATA Direct Connect with Internal Cable	258
17-7	Internal SATA Topology	259
18-1	USB 3.1 Gen1/2 Back Panel Topology	261
18-2	USB 3.1 Gen1/2 Internal Cable Topology	263
18-3	USB 3.1 Gen1/2 Re-driver Topology	265
18-4	USB 3.1 Gen2 Re-timer Topology	267
18-5	USB 3.1 Gen1 Detachable Docking Topology	268
18-6	USB 3.1 Gen1 Traditional Docking Topology	269
18-7	USB 3.1 Gen1 M.2 Topology	270
18-8	Device-Down	273
18-9	Device-On-Module	273
19-1	USB2_COMP Connection.....	275
19-2	Spacing Guideline for USB2_COMP.....	275
19-3	Sample Overcurrent Protection Circuit	276
19-4	USB 2.0 External Topology	277
19-5	USB On-The-Go Topology	278
19-6	USB 2.0 with M.2 Topology	279
19-7	USB 2.0 Flex/Internal Cable Topology with Daughter Card	280
19-8	USB 2.0 Flex/Internal Cable Topology without Daughter Card	282
19-9	USB 2.0 Device Down Topology	283
19-10	USB 2.0 External / Back Panel with Power Switch/ BC1.2 Charger Module/ MUX Topology ..	284



19-11	USB 2.0 Traditional Docking Topology.....	286
19-12	USB 2.0 Detachable Docking Topology.....	287
19-13	Daughter Card.....	290
19-14	Good Downstream Power Connection.....	291
20-1	Coffee Lake Platform USB Type-C Block Diagram.....	293
20-2	USB Type-C Receptacle Pin Map.....	293
20-3	Anatomy of a USB Type-C Receptacle.....	294
20-4	USB Type-C Connector Pin Map for a USB + DP x 2 Alternate Mode Example.....	294
20-5	USB 2.0 Only USB Type-C Connector.....	296
20-6	USB Type-C Receptacle Pin Map – USB 2.0 Only.....	297
20-7	USB 2.0 USB Type-C Topology.....	297
20-8	USB 2.0 with BC1.2 Charger Module / MUX / Power Switch Topology	298
20-9	BC1.2 Charger Module / MUX / Power Switch/USB PD (with BC 1.2 detection) Module Component Restrictions	299
20-10	USB 2.0 USB Type-C Port with MUX and Redriver Topology.....	299
20-11	USB Type-C Receptacle Pin Map - USB 3.1	301
20-12	USB Type-C Connector Connection (when the plug is 'Right Side Up')	301
20-13	USB Type-C Connector Connection (when the plug is 'Up Side Down')	301
20-14	USB 3.1 Gen1/Gen2 External Topology Without Active Mux	302
20-15	USB 3.1 Gen1/Gen2 Internal Cable Topology Without Active Mux	303
20-16	USB 3.1 Gen1/Gen2 Active Mux External Topology	304
20-17	USB 3.1 Gen1/Gen2 Active Mux Internal Cable Topology	307
20-18	Oval Anti-pad	309
20-19	USB 3.1 and DP x 2 USB Type-C Connector Mapping (Right Side Up)	309
20-20	USB 3.1 and DP x 2 USB Type-C Connector Mapping (Up Side Down).....	310
20-21	USB 3.1 and DP x 2.....	310
20-22	USB and DP x 4 USB Type-C Connector Mapping (Right Side Up).....	311
20-23	USB and DP x 4 USB Type-C Connector Mapping (Up Side Down)	311
20-24	USB 3.1 and DP x 4 Discrete Solution	311
20-25	System Design Example with USB Type-C Supporting DP as Alternate Mode	312
20-26	DP over USB-C- External Topology	312
20-27	DP over USB-C- Internal Cable Topology	313
20-28	DP AUX over USB-C- External Topology	314
20-29	DP AUX over USB-C- Internal Cable Topology	314
20-30	USB-C PD System Block Diagram for Clamshell Design.....	315
20-31	USB Type-C PTH Ground Void	318
20-32	USB Type-C SMT Pins Ground Void	319
20-33	USB Type-C Component Considerations	319
22-1	SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Cabled Load Configuration Diagram.....	324
22-2	SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Load Device Down Configuration Diagram.....	325
22-3	SoundWire Device Drive Impedance Adjustment	326
24-1	UART Topology	332
25-1	GSPI Topology.....	335
26-1	eSPI Single Load Topology	336
26-2	eSPI Single Load Topology	337
27-1	SMBus / SMLink (TCO Legacy Mode).....	341
27-2	SMBus / SMLink Connectivity (Advanced TCO Mode).....	342
27-3	Connectivity for Thermal Monitoring over SMBus	343
27-4	High Power/Low Power Mixed Vcc_SUSPEND / Vcc_CORE_ Architecture.....	343
28-1	SDXC Topology.....	348
29-1	LPC DATA 3 Load Daisy Chain Topology	350
29-2	LPC CLK Single Load Topology	351
30-1	SPI0 Single Load Topology	354



30-2	SPI0 2 Load Topology	355
30-3	SPI0 2 Load with EC Flash sharing Topology.....	356
30-4	SPI0 3 Load Topology	357
30-5	SPI0 3 Load with EC Flash Sharing Topology	358
32-1	HDA_SDI Single Load Audio Down Topology.....	363
32-2	HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST# Audio Down Topology.....	363
32-3	HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST# Branched Topology	364
32-4	DMIC_CLK and DMIC_DATA Branched Topology	365
32-5	PROC_AUDIO_SDO to HDACPU_SDI (CPU Out, PCH In) Topology.....	366
32-6	HDACPU_SDO to PROC_AUDIO_SDI/HDACPU_SCLK to PROC_AUDIO_CLK (PCH Out, CPU In) Topology.....	367
32-7	PCH to I ² S* Device Topology - I2S_MCLK/ I2Sx_SFRM/ I2Sx_TXD/ I2Sx_RXD	368
33-1	Intel® ME Architecture	370
33-2	C-Link Topology - To WLAN (CL_CLK1, CL_DATA1, CL_RST#)	373
33-3	Location of ZIF connector, FFC/FPC and Intel® APS Adapter	375
33-4	An Intel® Automatic Power Switcher (Intel® APS) Adapter with a FFC	375
33-5	An Intel® Automatic Power Switcher (Intel® APS) Adapter	376
33-6	Intel® Automatic Power Switcher (Intel® APS) Adapter connected	376
33-7	Intel® APS Connector	377
34-1	Intel® Coffee Lake IISS Diagram	384
34-2	An example of ISH_I2C and ISH_GP connection	388
34-3	System/Chassis Integration Options: Clamshell	390
34-4	System/Chassis Integration Options: Detachable	390
34-5	System/Chassis Integration Options: 2-in-1 with 360 Hinge	391
34-6	Other 2-in-1: Main A, G, M sensors behind the screen or in the Lid	391
34-7	System/Chassis Integration Options: pAO	392
34-8	Ambient Light Sensor Cross Section	393
34-9	Ambient Light Sensor Cross Section	393
34-10	Gyroscope X, Y and Z Orientation	395
34-11	Accelerometer X, Y and Z Orientation	396
34-12	Magnetometer X Y and Z Orientation.....	397
34-13	Simple SAR Sensor Control over WWAN Antenna Power.....	400
34-14	Co-SAR Sensor Control over WWAN Antenna and Wi-Fi Antenna Power.....	401
34-15	Adapter and Ribbon Cable	408
34-16	Proposed Location for ZIF Connector - under the keyboard	409
34-17	Proposed Location for ZIF Connector - under the keyboard	409
34-18	Connecting Debug Adaptor to an I2C sniffer.....	410
34-19	Proposed Usage of ZIF Connector Inside SST Compartment	410
34-20	Connecting Test/Debug Equipment to the Adapter	410
34-21	Dual-in-Line Header Example	413
35-1	Trusted Platform Module (TPM) / PCH Block Diagram.....	424
37-1	Example PIRQ Routing	431
39-1	Poorly-Documented M.2 Connector Schematics Symbols.....	435
39-2	Well-Documented M.2 Connector Schematics Symbol	436
39-3	PCI Express* Interface - Topology	437
39-4	SATA Interface - Topology	439
40-1	Unified Module Component Placement/Dimension	441
40-2	USB Connector.....	443
42-1	CNVi Platform Block Diagram	446
42-2	Module Mechanical Diagram - Source is PCI-SIG M.2 Spec Rev 1.0.....	451
42-3	Hybrid Key E'Pinout- Platform Side View	452
42-4	SD-1216 Module Pad-out for Supporting CNVi and Discrete 1216 Modules.....	456
42-5	Pin Out Scheme for Dual CNVi/Discrete 1216 Footprint.....	457
42-6	1216 Module Mechanical Diagram.....	462
42-7	Board Layout Example Showing Breakout from JfP 1216 pads	463



42-8	CNVi Clock Connections	465
42-9	Discrete Clock Connections.....	466
42-10	CNVi Power Connections with 1.8V Platform VR.....	469
42-11	CNVi Power Connections with Internal 1.8V LDO	470
42-12	CNVi Power up Sequence	474
42-13	Jumper-less Hybrid Key-E Routing Scheme.....	475
42-14	CNVio M.2 Topology Diagram	477
42-15	CNVio Device down Topology Diagram	478
42-16	CNVio Probing Components	480
42-17	CNVi BRI & RGI Single Load (DT) Topology Diagram	480
42-18	CNVi BRI & RGI Single Load (RSP) Topology Diagram	481
42-19	Jefferson Peak Crystal Input to CFL Topology Diagram	482
42-20	Coex UART for Connectivity/Modem in 3-way Configuration	484
42-21	PCIe Common Clock Configuration	486
42-22	PCIe CLKREQ# Timing	487
43-1	Antenna Placement Option 1	494
43-2	Antenna Placement Option 2	495
43-3	Potential Solution for Metallic Chassis with Lid-Closed Operation.....	496
44-1	Telecom Safety Considerations-Generic Block Diagram and Isolation.....	501
44-2	Telecom Safety Considerations-Stringent Test in Metallic Mode	501
44-3	Board Level Design Considerations-Isolation.....	502
44-4	Board Level Design Considerations-Surge (Distances inside TNV)	503
44-5	Board Level Design Considerations-Example of Wrong Implementation	503
45-1	CFL Flow Diagram for SYS_PWROK/PCH_PWROK Generation.....	506
45-2	CFL Flow Diagram for RSMRST_PWRGD# Generation	506
45-3	Timing Diagram for G3 to S0/M0 [Deep Sx Platform]	512
45-4	Timing Diagram for G3 to S0/M0 [Non-Deep Sx Platform]	514
45-5	Timing Diagram for S0/M0 to G3 [Deep Sx Platform]	516
45-6	Timing Diagram for S0/M0 to G3 [Non-Deep Sx Platform]	517
45-7	Timing Diagram for Warm Reset (Host Partition Reset w/o Power Cycle).....	518
45-8	Timing Diagram for Cold Reset (Host Partition Reset w/ Power Cycle) and Global Reset [Non-Deep Sx Platform].....	519
45-9	CFL H Rail to Rail Sequencing Requirement for Deep Sx Configured System	528
45-10	CFL H Rail to Rail Sequencing Requirement for Non-Deep Sx Configured System	529
45-11	DSW_PWROK Requirement for Power Loss	532
46-1	Primary Debug Port-JTAG Topology for Dual Scan Chain Only Design	537
46-2	Primary Debug Port-JTAG Topology for Dual Scan Chain Only Design	538
46-3	Primary Debug Port: Observation Ports routing	542
46-4	Primary Debug Port: Observation Ports Routing	543
46-5	Primary Debug Port-HOOK, VCC_OBS signals Route Map	547
46-6	Primary Debug Port-HOOK, VCC_OBS signals Route Map	548
46-7	Primary Debug Port-XDP_PRESENT# Connectivity	553
46-8	Primary Debug Port-XDP_PRESENT# Connectivity	554
46-9	Secondary Debug Port - PCH Chipset Test Interfaces	560
46-10	Connector Less Routing Topology	565
46-11	Connector Less Routing Topology	566
46-12	60-pin XDP Connector System Keep-Out Diagram	571
46-13	Primary (Merged) CMC Gen 1 Keep out Specification.....	573
46-14	Primary (Merged) CMC Pads Layout (Primary Side).....	574
46-15	CMC Gen 1 - Captive Screw	575
46-16	CMC Gen 1- Retention Nut	576
46-17	Secondary CMC Keep Out Specification	577
46-18	Secondary (OBS) CMC Pads Layout	578
46-19	Ground Stitching/Return Vias Example.....	580
46-20	Bypass Capacitor	580



46-21	Termination after Last Receiver	581
46-22	Termination Prior to Last Receiver	581
46-23	Intel DFM HVM Test Solution High Level View	582
47-1	Thermal Management Option 1	585
47-2	Thermal Management Option 2	585
48-1	Flow Chart of Acoustic Noise Generation	586
48-2	Example Vibration (Left) and Acoustic Radiation (Right) Pattern Generated by One Capacitor Mounted in the Center of Test Board	587
48-3	Example: Single-sided Mounted Capacitor Generates 49 dB Sound Pressure Level (SPL) while Symmetrically Mounted Capacitor Generate 25 dB	588
48-4	Before (Top) and After (Bottom) the Implementation of Dynamic Periodicity Alteration ..	590
49-1	Ground Ring/ PTH	592
49-2	Example - Ground ring	593
49-3	Power Plane Decoupling	594
49-4	Example for Connector Decoupling	595
49-5	Example for Traces Crossing Planes	595
49-6	Stitching Capacitors Placement	596
49-7	VRM Input Filter	597
49-8	Measurement Results	597
49-9	Filtering Circuit for AC Jack	597
49-10	Filter for DMIC_CLK	598
49-11	Filter for LPC_CLK	598
49-12	Noise Comparison - With Shield and Without Shield	599
49-13	SPI Cable Shielding	599
49-14	0-Ohm Series Resistors for Crystal Signals	601
49-15	De-coupling Capacitor for Sensitive Net	602
49-16	Measurement Results	603
49-17	Improper Shielding for USB Connectors	603
49-18	Proper Shielding For Connectors	604
49-19	USB3 Type-A Connector Shielding	604
49-20	Filter Circuit for Audio Jack	605
49-21	Shielded FFC Cable Design Recommendations	606
49-22	PCB CMC	607
49-23	Type C ESD Protection	609
50-1	CFL H 6+2 CPU Cavity Keep Out Zone Recommendation	612
50-2	CFL H 8+2 Refresh CPU Cavity Keep Out Zone Recommendation	612
50-3	VCCSA Ripple (Yellow) vs PLL Phase Error (TIE)	616
50-4	IST Trigger Point Implementation Requirement	618
50-5	Current Sense Resistor Recommendation	619
50-6	Minimized Loop Inductance Example (R)unway	623
50-7	(E)dge Decoupling Capacitor Placement	623
50-8	CNL PCH-H Power Rail Isolation Example	624
50-9	CNL PCH-H Power Rail Isolation Example	625
50-10	CNL PCH-H 1.05V VRM Senseline Isolation Example	625
50-11	CNL PCH-H Sensitive Rail Filtering and Routing Recommendation	626
50-12	Scenario 1: Platforms without 1.8V External VR Connected to PCH Recommendation	627
50-13	Scenario 2: Platforms with 1.8V External VR Connected to PCH Recommendation	629
50-14	Coffee Lake H-Processor Land Pattern Guidance	631
50-15	Cannon Lake PCH-H Land Pattern Guidance	632
51-1	IMVP8 VR Block Diagram	636
51-2	Input Voltage Droop Caused by dv/dt Event at Output	638
51-3	Example of Processor Vcc_SENSE/Vss_SENSE Package Sensing	639
51-4	Hybrid Power Boost (HPB) Battery Charger	649
51-5	Narrow VDC (NVDC) Battery Charger	649
51-6	Detailed View of USB-PD Subsystem	651



51-7	Modes of Operation	651
51-8	Relationship Between Platform Power Levels.....	653
51-9	HPB Battery Charger with Psys Implementation	654
51-10	NVDC Battery Charger with Psys Implementation	655
51-11	Information Sources and Flow Diagram	657
51-12	DBPT Top Level Block Diagram	659
51-13	Block Diagram of In-Pack Fuel Gauge with DBPT	661
51-14	Block Diagram of 1S Fuel Gauge with 2S Pack	662
52-1	System Instrumentation Block Diagram	666
52-2	Power Instrumentation Setup	666
52-3	Flexible Instrumentation Overview	667
52-4	FIP Board versus Non-FIP Board	668
52-5	Layout for Inner Layout Current Sense Resistors (impedance coupon) Calibration	669
52-6	Layout for Current Sense Resistors Calibration for Top and Bottom Layers	670
52-7	FIP/non-FIP Symbol Design Examples-1.....	673
52-8	FIP/non-FIP Symbol Design Examples-2.....	673
52-9	Variations in IR Drop due to Via Placement.....	674
52-10	PCB Placement	675
52-11	FIP and Non-FIP Gerber/PCB	676
52-12	DuPont Header Connector	677
52-13	FIP Top/Bottom Side Current Sense Resistor Calibration - Routing Overview	679
52-14	FIP Inner Layer Impedance Coupon Calibration - Routing Overview	680

Tables

1-1	CFL H Platform Windows* OS Support.....	35
2-1	Stack-Up and PCB Considerations Reference Documents.....	37
2-2	CFL H Type 3 PCB Stack-Up Parameter Values (Microstrip)	39
2-3	CFL H Type 4 PCB Stack-Up Parameter Values (Microstrip)	39
2-4	CFL H Type 3 PCB Stack-Up Parameter Values (Dual-Stripline)	39
2-5	CFL H Type 4 PCB Stack-Up Parameter Values (2 x 2+ 1 Oz Dual-Stripline)	40
2-6	CFL H Type 4 PCB Stack-Up Parameter Values for (2 x 2+ 0.5 Oz Dual-Stripline)	40
2-7	CFL H Type 4 PCB Stack-Up Parameter Values (Stripline 1-x-1/1-x-1+).....	42
2-8	CFL H Type 3 PCB Stack-Up Parameter Values (Stripline 8/10 Layer)	42
2-9	CFL H Breakout Geometries for Type 3 and Type 4 PCB	47
2-10	CFL H Microstrip Routing Geometries for Type 3 & Type 4 PCB	48
2-11	CFL H Stripline routing geometry for Type-3 PCB	49
2-12	CFL H Dual Stripline routing geometry for Type-3 PCB.....	49
2-13	CFL H Dual Stripline routing geometry for Type-4 (2-x-2+ 1Oz.)PCB	50
2-14	Electrical Limits of LH Material Properties.....	52
2-15	Type 4 PCB Via Combinations	54
2-16	Max Root Square Sum (RSS) Length versus Transfer Speed.....	60
3-1	General Dual-Stripline Support.....	67
3-2	Differential Transitional Via Layout Recommendations	77
3-3	General Differential Pair Length Matching	79
4-1	System Memory Configurations Supported by Guidelines in this Chapter.....	91
4-2	System Memory Interface Guideline Terminology and Descriptions.....	92
4-3	System Memory Configuration Details Covered in this Section	93
4-4	CFL-H DDR4 ECC SO-DIMM 2DPC Signal Routing Guidelines.....	95
4-5	CFL-H DDR4 ECC SO-DIMM Length and Matching Guidelines	98
4-6	System Memory Configuration Details Covered in this Section	99
4-7	System Memory Configuration Details Covered in this Section	102
4-8	CFL-H DDR4 SO-DIMM 1DPC Signal Routing Guidelines	104
4-9	System Memory Configuration Details Covered in this Section	107
4-10	System Memory Configuration Details Covered in this Section	109



4-11	CFL-H DDR4 1Rx16 Memory Down Routing Guideline.....	112
4-12	CFL-H DDR4 1Rx16 Memory Down Length Matching Guidelines	114
4-13	System Memory Configuration Details Covered in this Section	115
4-14	CFL-H DDR4 x8 Memory Down Routing Guideline	118
4-15	CFL-H DDR4 x8 Memory Down Length Matching Guidelines	120
4-16	System Memory Configuration Details Covered in this Section	121
4-17	System Memory Configuration Details Covered in this Section	123
4-18	System Memory Configuration Details Covered in this Section	125
4-19	CFL-H LPDDR3 x32 Memory Down Routing Guidelines.....	127
4-20	CFL-H LPDDR3 x32 Memory Down Length Matching Guidelines	128
4-21	ODT Signals Connectivity Table	129
4-22	DIMMs/DRAMs DM Signals Connectivity Table.....	129
4-23	CFL H Guidelines for Vias Separation	131
4-24	DDR4 SODIMM Power Plane Decoupling	135
4-25	DDR4 Memory Down Power Plane Decoupling	136
4-26	LPDDR3 x32 Power Plane Decoupling	138
5-1	DisplayPort* Bit Rates	141
5-2	Supported Voltage and Pre-emphasis Levels.....	142
5-3	DisplayPort* Signals	142
5-4	Optimization Table for all Topologies	143
5-5	CFL S DT/AIO Display Port Main Link Topologies Guidelines	144
5-6	CFL H Display Port Main Link Topologies Guidelines	144
5-7	CFL S AIO DisplayPort* Main Link Muxed Port Sharing Topology Guidelines	144
5-8	CFL H DisplayPort* Main Link Muxed Port Sharing Topology Guidelines	145
5-9	CFL H DisplayPort* Docking Topology with Re-driver Guidelines	145
5-10	CFL H DisplayPort* Multiplexed Docking Topology with Re-driver Guidelines	146
5-11	CFL H DisplayPort* Main Link Internal Cable Topology Guidelines	147
5-12	CFL DT/AIO DisplayPort* Auxiliary Channel Routing Guidelines	149
5-13	CFL H DisplayPort* Auxiliary Channel Routing Guidelines	149
5-14	DDI Disabling and Termination Guidelines	154
5-15	DDI Disabling and Termination Connections	154
6-1	eDP* Reference Specification	155
6-2	eDP* Compliance Specification	155
6-3	eDP* Signal Groups	155
6-4	eDP* Cable Parameters	155
6-5	Optimization Table for all Topologies	156
6-6	CFL eDP* Main Link Topology for HBR and HBR2	157
6-7	CFL eDP* Main Link Auxiliary Channel Topology	158
6-9	CFL eDP* Aux Channel DP to VGA Converter Topology	159
6-8	CFL H Display Port Main Link Direct DP to VGA Topology	159
6-10	DISP_RCOMP Guideline	161
6-11	eDP* Disabling and Termination Guidelines	161
7-1	Mapping of HDMI* Signals for DDI Ports	164
7-2	HDMI* Interface Reference Documents.....	164
7-3	HDMI* Interface Compliance Documents	165
7-4	HDMI* Signals	165
7-5	Optimization Table for all Topologies	165
7-6	CFL HDMI 1.4* Main Link Cost-reduced Level Shifter Motherboard Topology Guidelines	166
7-7	CFL H HDMI 1.4* Main Link Active Level shifter Motherboard Topology Guidelines	167
7-8	CFL H HDMI 1.4* Main Link Active Level shifter Multiplexed Topology Guidelines	168
7-9	CFL H HDMI 1.4* Main Link Active Level shifter Docking Topology Guidelines.....	169
7-10	CFL H HDMI 1.4* Main Link Active Level shifter Docking Multiplexed Topology Guidelines ...	169
7-11	CFL H HDMI 1.4* Internal Cabled Solution Topology Routing Guidelines	170
7-12	CFL H HDMI 1.4* DDC Routing Guidelines.....	173



7-13	CFL H LSPCON Main Link Direct MB Topology Guidelines	176
7-14	CFL H Type 3 HDMI 2.0 DDC Topology	177
8-1	PCI Express* Signal Groups	179
8-2	Coffee Lake H Design Topologies (Add-In Card and Device Down)	181
8-3	Few Supported Normal and Lane-reversed Bifurcation Configurations	186
8-4	PCIe* Configurations	186
8-5	Desktop Form Factor AC Coupling Capacitor Guidelines	188
8-6	AIO Form Factor AC Coupling Capacitor Guidelines	189
8-7	AC Coupling Capacitor Guidelines	190
8-8	AC Coupling Capacitor Guidelines	191
8-9	Processor PCI Express* Compensation Signal Routing Guidelines	192
9-1	DMI Signal Groups	193
9-2	DMI 2-Via Topology Routing Guidelines	194
11-1	Acronyms	198
11-2	Supported Thunderbolt™ Configuration - Inputs	199
11-3	Supported Thunderbolt™ Configuration - Outputs	199
11-4	VBUS Power Provisioning with Number of Thunderbolt™ Ports	200
11-5	Thunderbolt™ VBUS Source Electrical Parameters	201
11-6	Thunderbolt VCONN Source Electrical Requirements	201
11-7	Supported Alpine/Titan Ridge Security Level	202
11-8	Alpine/Titan Ridge S3/S4 Wake Support Enabled	202
11-9	Alpine/Titan Ridge S3/S4 Wake Support Disabled	202
11-10	Thunderbolt™ Compliance Specification	203
11-11	Thunderbolt™ High Speed Interface	203
11-12	Alpine/Titan Ridge High Speed Signals	204
11-13	CFL DisplayPort to TBT Main Link Routing Guideline	205
11-14	CFL DisplayPort to TBT AUX Link Routing Guidelines	205
11-15	Thunderbolt™-ready Motherboard Requirement	205
11-16	Thunderbolt™ Layer Utilization	208
11-17	Supported Flash for Alpine/Titan Ridge	209
12-1	Platform Clocks and Associated Signal Details and Descriptions	212
12-2	ITP_XDP Differential Clock Routing Guidelines	213
12-3	CPU Differential Clock Routing Guidelines	214
12-4	PCIe* Differential Clock to Add-in Card Routing Guidelines	215
12-5	PCIe* Differential Clock to Down Device Routing Guidelines	216
12-6	SRC Request Signal Routing Guidelines	217
12-7	24 MHz Crystal Specifications	218
12-8	PCH-H Platform Crystal XTAL_IN/OUT Routing Guidelines	219
12-9	XCLK Bias Reference Routing Guideline	221
13-1	Reference Specification	222
13-2	RTC Routing Guidelines	223
14-1	Asynchronous and Sideband Legacy Signal Group	227
14-2	Asynchronous and Sideband Signal General Routing Guideline	228
14-3	PROCHOT# Routing Guidelines	230
14-4	CATERR# Routing Guidelines	230
14-5	PROCPWRGD Routing Guidelines	231
14-6	VCCST_PWRGOOD Routing Guidelines	232
14-7	THERMTRIP# Routing Guidelines	232
14-8	RESET# Routing Guidelines	233
14-9	BPM#[3:0] Routing Guidelines	235
14-10	PM_SYNC Routing Guidelines	235
14-11	PM_DOWN Routing Guidelines	236
14-12	PROC_TRIGIN Routing Guidelines	236
14-13	PROC_TRIGOUT Routing Guidelines	237
14-14	SVID Bus Routing Guidelines	238



14-15	SVID Minimum Spacing Guidelines	238
16-1	PCH PCI Express* Signal Groups.....	242
16-2	PCH PCI Express* Device Down Routing Guidelines	243
16-3	PCH PCI Express* Add-In Card Connector Routing Guidelines	244
16-4	PCH PCI Express* with Internal Cable Routing Guidelines.....	245
16-5	PCH PCI Express* with Internal Cable Routing Length versus Cable Loss	246
16-6	PCH PCI Express* Compensation Routing Guidelines	246
16-7	PCH PCIe* Configuration Lane Reversal Mapping.....	248
17-1	SATA Reference Documents	250
17-2	SATA Compliance Documents	250
17-3	SATA Signal Groups	250
17-4	Routing Guidelines for mSATA and Direct Connect Topology	255
17-5	SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values	256
17-6	Internal Connector and Cable Specification.....	256
17-7	SATA Direct Connect without daughter card and with Internal Cable Guidelines.....	257
17-8	SATA Direct Connect with Internal Cable Guidelines	258
17-9	Routing Guidelines for Internal SATA Topology	259
18-1	Coffee Lake Processor USB Overcurrent Pins	260
18-2	USB 3.1 Reference Documents	260
18-3	USB 3.1 Compliance Documents	260
18-4	USB 3.1 Gen2 Interface Signals.....	260
18-5	USB 3.1 Gen1/2 Back Panel Routing Guidelines	261
18-6	USB 3.1 Gen1/2 Internal Cable Topology Routing Guidelines	264
18-7	USB3.1 Gen1 Internal Cable Differential Insertion Loss Requirements	264
18-8	USB 3.1 Gen1/2 Re-Driver Topology Routing Guidelines.....	266
18-9	USB 3.1 Gen2 Re-timer Topology Routing Guidelines	267
18-10	USB 3.1 Gen1 Detachable Docking Topology Routing Guidelines.....	268
18-11	Trade off of Internal Cable Loss on Margin	269
18-12	USB 3.1 Gen1 Traditional Docking Topology Routing Guidelines	269
18-13	USB3.1 Gen1 M.2 Topology.....	270
18-14	Example of Mobile Internal Connector Pin Assignment and Description for Two-Port USB 3.1 Gen2*	272
19-1	USB 2.0 Reference Documents	274
19-2	USB 2.0 Compliancy Documents	274
19-3	USB 2.0 Signal Groups	274
19-4	USB2_COMP Routing Guidelines.....	275
19-5	USB 2.0 External Topology.....	278
19-6	USB 2.0 On-The-Go Topology	279
19-7	USB 2.0 with M.2 Topology	280
19-8	USB 2.0 Flex/Internal Cable Topology with Daughter Card	281
19-9	USB 2.0 Internal Cable Differential Insertion Loss Restrictions	281
19-10	USB 2.0 Flex/Internal Cable Topology without Daughter Card	282
19-11	USB 2.0 Internal Cable Differential Insertion Loss Restrictions	282
19-12	Routing Guidelines for USB 2.0 Device Down Topology	283
19-13	USB 2.0 External / Back Panel with Power Switch / BC1.2 Charger Module / Mux Topology Routing Guidelines	285
19-14	BC1.2 Charger Controller/MUX/Power switch/USB PD (with BC1.2 detection) Module Component Restrictions	285
19-15	USB 2.0 Traditional Docking Topology Routing Guidelines	286
19-16	USB 2.0 Detachable Docking Routing Guidelines	287
19-17	USB 2.0 Trade-off on Internal Cable Differential Insertion Loss on Margins	288
19-18	Example of Internal Connector Pin Assignment and Description.....	289
20-1	USB Type-C Supported Configuration on Coffee Lake	295
20-2	USB 2.0 with BC1.2 Charger Module / MUX / Power Switch Topology Routing Guidelines	298
20-3	USB 2.0 to USB Type-C Port Routing Guideline with MUX and Redriver Topology	299



20-4	Routing Guidelines- USB 3.1 Gen2- External Topology Without Active Mux	302
20-5	Routing Guidelines- USB 3.1 Gen1- External Topology Without Active Mux	302
20-6	Routing Guidelines- USB 3.1 Gen2- Internal Cable Topology Without Active Mux	303
20-7	Routing Guidelines- USB 3.1 Gen1- Internal Cable Topology Without Active Mux	304
20-8	Routing Guidelines- USB 3.1 Gen2 Active Mux External Topology (With Re-driver Based Active Mux)	305
20-9	Routing Guidelines- USB 3.1 Gen1 Active Mux External Topology (With Re-driver Based Active Mux)	305
20-10	Routing Guidelines- USB 3.1 Gen2 Active Mux External Topology (With Re-timer Based Active Mux)	306
20-11	Routing Guidelines- USB 3.1 Gen1 Active Mux External Topology (With Re-timer Based Active Mux)	306
20-12	Routing Guidelines- USB 3.1 Gen1/Gen2 Active Mux Internal Cable Topology (With Re-driver Based Active Mux)	307
20-13	Routing Guidelines- USB 3.1 Gen1/Gen2 Active Mux Internal Cable Topology (With Re-timer Based Active Mux)	308
20-14	Routing Guidelines- DP over USB-C External- B Topology	313
20-15	Routing Guidelines- DP over USB-C- Internal Cable Topology	313
20-16	Routing Guidelines- DP AUX over USB-C- External Topology	314
20-17	Routing Guidelines- DP AUX over USB-C- Internal Cable Topology	314
20-18	CC Signals Routing Guide	318
21-1	Signals Required Cap or Pull-Down Resistor	321
21-2	Signals Recommended with Cap or Pull-down Resistor Sites	322
21-3	Signals Required Pull-up Resistor	322
22-1	SoundWire Signals	323
22-2	SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Cabled Load Routing Guidelines	324
22-3	SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Load Down Device Routing Guidelines	325
22-4	SoundWire Device Drive Impedance Guidelines	326
23-1	Reference Specifications	327
23-2	I ² C* Signals	327
23-3	I ² C* Signal Routing Summary	328
23-4	Bus Capacitance Reference Chart	328
23-5	Bus Capacitance / Pull-Up and Current Assist Strength Settings	329
24-1	UART Signals	332
24-2	UART Routing Guideline for Motherboard	333
25-1	GSPI Signals	334
25-2	GSPI Routing Guideline for CFL PCB	335
26-1	eSPI Signals	336
26-2	eSPI Single Load Routing Guidelines	337
27-1	SMBus and SMLink Signals	339
27-2	SMBus Length Matching Summary	341
27-3	Bus Capacitance Reference Chart	344
27-4	Bus Capacitance/Pull-Up Resistor Relationship	345
27-5	Compliance Documents	346
28-1	SDXC Signals	347
28-2	SDXC Routing Guidelines for CFL Motherboard	348
29-1	LPC Signal Descriptions	349
29-2	Routing Guidelines for LPC DATA 3 Load Daisy Chain Topology	350
29-3	Routing Guidelines for LPC CLK Single Load Topology	351
30-1	Acronyms	353
30-2	SPI0 Signals	353
30-3	Single Flash Topology Routing Guidelines	354
30-4	Routing Guidelines for SPI0 2 Load Topology Routing Guidelines	355



30-5	Routing Guidelines for SPI0 2 Load with EC Flash Sharing Topology	356
30-6	SPI0 3 Load Topology Routing Guidelines.....	357
31-1	SPI1 Single Load Touch Routing Guideline.....	361
32-1	Audio Signals	362
32-2	HDA_SDIN/HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST#/ Audio Down Routing Guidelines . 363	
32-3	HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST#/DMIC_CLK/DMIC_DATA Branched Routing Guidelines	365
32-4	HDACPU_SDI Audio Down Routing Guidelines.....	366
32-5	HDACPU_SDO/HDACPU_SCLK Routing Guidelines	367
32-6	I ² S* Audio Down Routing Guidelines	368
33-1	Power Delivery Summary for Intel® ME SubSystem.....	372
33-2	Intel® ME C-Link Signals and Signal-Integrity Design Guidelines	373
33-3	C-Link Topology Guidelines	373
33-4	C-Link General Guidelines	373
33-5	Intel® Automatic Power Switcher (Intel® APS) Connector	378
33-6	Pin Location for Dual-in-Line Connector	378
33-7	Corporate Firmware behavior	379
33-8	Hardware and EC firmware Requirements Checklist	380
34-1	Sensor Types and Supported Form Factors.....	385
34-2	ALS Characteristics	392
34-3	Rate Table: The cumulative distribution of Gyroscope output at 200 dps	404
34-4	Variations of Gyroscope output at different mDPS	405
34-5	Pin Location for Dual-in-Line Connector	411
34-6	18-pin ZIF Connector Pinout	412
34-7	Pin Location for Dual-in-Line 0.1" Header.....	413
34-8	Ambient Light Sensor (ALS) Details.....	414
34-9	Gyroscope Details.....	414
34-10	Magnetometer Details	414
34-11	Accelerometer Details	415
34-12	Pressure Sensor Details	415
34-13	Optional 2nd Accelerometer (for 360o hinge designs)	415
34-14	Intel Sensor Solution BOM Checklist.....	416
34-15	Sensors Debug Connector Checklist	416
34-16	FW Debug connector Checklist.....	416
34-17	General Checklist.....	416
34-18	Power Rails Checklist	417
34-19	Coffee Lake Sensors Interrupt/GPIO Checklist	417
35-1	TPM Reference Documents.....	423
35-2	TPM Compliance Documents.....	423
35-3	Trusted Platform Module (TPM) Signals	424
36-1	Platform Reset Signals	425
36-2	Minimum Assertion Time Stretching Options.....	429
37-1	IOAPIC Interrupt Inputs 16 Through 23 Usage.....	430
38-1	Signals Group	432
38-2	Critical Signals Routing Summary	433
38-3	Frequency Sensitivity	433
39-1	References	434
39-2	TX and RX - PCIe Gen1 Layout Guidelines	437
39-3	TX and RX - PCIe Gen2 Layout Guidelines	437
39-4	TX and RX - PCIe Gen3 Layout Guidelines	437
39-5	SATA M.2 Layout Guidelines.....	439
39-6	SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values	440
40-1	HD/FHD Webcam Module Connector/Pinout	441
41-1	Reference Documents	444



42-1	RF Companion Module 2230 Pin List.....	448
42-2	Connectivity Interfaces for Different M.2 2230 Cards.....	455
42-3	RF Companion Module 1216 Pin List (CNVi only).....	457
42-4	CNVi Module SKUs.....	463
42-5	Intel Discrete Module SKUs.....	464
42-6	SoC Straps Related to CNVi and Clock Sharing	467
42-7	Input/Output Electrical Specifications	470
42-8	CNVio Recommended Routing Parameters	477
42-9	CNVio M.2 Topology Values	478
42-10	CNVio Device Down Topology Values	478
42-11	Topology Guidelines	479
42-12	General Guidelines	479
42-13	CNVi BRI & RGI Single Load (DT) Topology Values	481
42-14	CNVi BRI & RGI Single Load (RSP) Topology Values	481
42-15	General Guidelines	481
42-16	Jefferson Peak Crystal Input to CFL Topology Values	482
42-17	External Topology Guidelines	483
42-18	Power-up CLKREQ# Timing	487
42-19	Power-up PERST# Timing	488
43-1	Antenna Performance Recommendations	491
43-2	Isolation Recommendations	491
43-3	Recommendations for Different Modes of Operation	491
43-4	Additional Recommendations for Wi-Fi MIMO Operation	497
43-5	Intel WWAN Antenna Tuning GPIO Description	498
43-6	M.2 Module Specifications	498
43-7	M.2 Module Recommended values for Tuners	499
43-8	In-Device Coexistence Interface	499
44-1	Component Placement Review Checklist	504
44-2	General Routing Review Checklist	504
45-1	CFL Interface Signals List	507
45-2	CFL Power Sequence Related Power Rails	510
45-3	System with M3 State Supported	510
45-4	Legend for Signals in Transition Waveforms	511
45-5	Platform Sequencing Timing Parameters.....	520
45-6	Allowed VCCST and VCCPLL_OC Power State Combinations.....	527
45-7	Rail-to-Rail Sequencing Requirements.....	530
46-1	Coffee Lake Run Control Tool Debug Port Options	534
46-2	Run Control Debug Hooks Routing Options	536
46-3	Primary Debug Port - Dual Scan Chain Only Routing Guidelines	539
46-4	Primary Debug Port - Observation Pins Routing Guidelines	544
46-5	Primary Debug Port - HOOK, VCC_OBS, SCL/SDA, Ground signals Routing	549
46-6	Primary Debug Port - XDP_PRESENT Routing Guidelines	554
46-7	Primary XDP Connector Pinout	555
46-8	Primary CMC Connector Pinout.....	557
46-9	Secondary Debug Port- OBS Pins Routing Requirements	559
46-10	Secondary XDP Connector Pinout	561
46-11	Secondary XDP Connector Pinout	562
46-12	Secondary CMC Connector Pinout	563
46-13	Connector Less Debug Hooks Routing Guidelines	567
47-1	Platform Thermal Management Reference Documents	584
47-2	Signal Groups	584
49-1	Sensitive Nets	601
49-2	Examples for CMC Components Selection	607
49-3	Filter requirements for other interfaces	608
49-4	Examples for ESD Components Selection.....	608



49-5	Other Critical Decoupling Capacitors and EMI Filtering Components	609
49-6	TYPE C CMC guidelines	609
50-1	Reference Documents	611
50-2	CFL H 6+2 Bulk Decoupling Example	613
50-3	Decoupling Requirements for CFL H 6+2 Processor.....	613
50-4	CFL H 8+2 Bulk Decoupling Example.....	614
50-5	Decoupling Requirements for CFL H 8+2 Processor.....	614
50-6	IST (IFDIM) Testing Requirements and Recommendations.....	617
50-7	Coffee Lake SKU IFDIM/IST Ballout Pins on Processor.....	618
50-8	Decoupling and Power Connection Requirements for CNL PCH-H	620
50-9	Filter Requirements for CNL PCH-H	621
50-10 A capacitor Derating example	622
50-11	Land Pattern Reference Document	629
50-12	PCB Pad Definitions.....	630
51-1	Differences between Power Maps	634
51-2	Estimated Power Deltas between Different Configurations	634
51-3	Enable Signal Implementations for VccST and VccPLL_OC	635
51-4	Package Sensing Recommendations	639
51-5	General Processor VR Parameters for CFL H62, CFL H42 and CFL H82	640
51-6	Processor VR Overshoot values.....	642
51-7	Processor VR Design Values	642
51-8	Electrical Requirements for VCCIO VR	644
51-9	Electrical Requirements for V1.05A VR.....	644
51-10	Electrical Requirements for VTT VR	644
51-11	Electrical Requirements for VDDQ VR	645
51-12	Electrical Requirements for V3.3_DSWVR	645
51-13	Electrical Requirements for V5A VR	645
51-14	Electrical Requirements for V1.8A VR	645
51-15	Electrical Requirements for V2.5U VR	645
51-16	Sustained and Transient Power Levels with different PD Architectures	647
51-17	Benefits and Trade-offs of the Different Chargers.....	650
51-18	Access Availability of the Various Psys Configuration Parameters.....	657
51-19	RPSYS Examples	658
51-20	Battery Discharge Capability Recommendations	662
52-1	Base Design Proposal	671
52-2	FIP Design Proposal (with 4x Layer Addition).....	672
53-1	Key Design References for Power Optimized Designs	683



Revision History

Document Number	Revision Number	Description	Revision Date
571391	0.5	<ul style="list-style-type: none">Initial Release	January 2017
571391	0.7	<p>Chapter 11, "Hybrid Graphics"</p> <ul style="list-style-type: none">Switchable Graphic was removed. Hybrid Graphics content was added. <p>Chapter 16, "PCH PCI Express* Interface Design Guidelines"</p> <ul style="list-style-type: none">Replaced Break-In Max Length segment terminology with Post-AC Capacitor Max Length segmentCorrect AC Cap comment in RCOMP section with the correct term Series Resistor <p>Chapter 17, "SATA Interface Guidelines"</p> <ul style="list-style-type: none">Replaced "Breakin Max length" changed to "post-AC capacitor main route length" in topology tables <p>Chapter 20, "USB Type-C"</p> <ul style="list-style-type: none">Updated the diagrams from figures Figure 20-14 to Figure 20-19.Added general design guidelines in the 'Notes' section at the end of the Section 20.3.2.Deleted the OC protection diagram, GPIO mapping table, Debug Alternate Mode sub-section and EC-less USB-C sub-section.Added Figure 20-9 in USB2 sub-section containing component restrictions.Added reference documents and links in the last sub-section 19.3.10Updated the platform block diagram in Figure 20-1.Corrected the mils to mm typo in USB2 DG Table 20-3. <p>Chapter 22, "MIPI SoundWire* Interface Design Guidelines"</p> <ul style="list-style-type: none">In Table 22-2<ul style="list-style-type: none">Updated M-Cable reference inUpdated supported operating frequency to show 6MHzAdded note 2In Table 22-3<ul style="list-style-type: none">Updated supported operating frequency to show 6MHzAdded note 7In Table 22-4<ul style="list-style-type: none">Updated supported operating frequency to show 6MHzAdded note 2 <p>Chapter 23, "I²C* Interface Design Guidelines"</p> <ul style="list-style-type: none">Updated Section 23.1.2.1, "General Design Considerations"Updated Table 23-4, "Bus Capacitance Reference Chart":Updated Table 23-5, "Bus Capacitance / Pull-Up and Current Assist Strength Settings" <p>Chapter 27, "SMBus 2.0/SMLink Interface Design Guidelines"</p> <ul style="list-style-type: none">External Pull-up required for the SMBus and SMLink interfaces <p>Chapter 28, "Secure Digital Card with Extended Capacity (SDXC) Interface Design Guidelines"</p> <ul style="list-style-type: none">Removed SD_VDD2_PWR_EN# signal which is not usedExternal Pull-up resistor not required on SD_DATA; CLK and CMD.Updated Figure 28-1, "SDXC Topology"	May 2017



Document Number	Revision Number	Description	Revision Date
571391	0.7	<p>Chapter 32, "Legacy Audio Interface Design Guidelines"</p> <ul style="list-style-type: none">• Corrected trademarks• Added the Embedded Display Audio Interface line to the legacy audio list prior to Section 32.1• Corrected C1 placement in Figure 32-2.• Added note 4 and 5 in Table 32-2.• Added note 5 to Table 32-3.• Updated Figure 32-3 to remove DMIC name as Figure 29-4 is specifically for DMIC.• Updated Table 32-4 and Table 32-5.• Added max length for B0 + M1 Table 32-6.• Simplified Figure 32-4 and Figure 32-5 removing M2 and BI.• Minor adjustments to grammar and readability <p>Chapter 49, "Electromagnetic Compatibility"</p> <ul style="list-style-type: none">• Removed CPU/PCH Noise in Section 49.3, "Critical Signals"• Updated Section 49.3.4, "Crystal (Xtal) RF Immunity" <p>Chapter 50, "Processor and PCH Power Integrity Recommendations"</p> <ul style="list-style-type: none">• Updated Table 49-3 <p>Chapter 52, "Power Delivery"</p> <ul style="list-style-type: none">• Power Map excel sheet - part of PDG zip file• Section 52.3• Table 52-2, Table 52-3, and Table 52-4	May 2017
571391	0.71	<p>Chapter 4, "System Memory Interface Design Guidelines"</p> <ul style="list-style-type: none">• Removed Section 4.5 MD 1Rx16 double-T.• Added Section 4.8, "CFL H DDR4 Mixed SODIMM and MemoryDown x8 Daisy-Chain Topology"• Added Section 4.8, "CFL H DDR4 Mixed SODIMM and MemoryDown x8 Daisy-Chain Topology"	May 2017
571391	1.0	<p>Chapter 2, "Stack-Up and PCB Considerations"</p> <ul style="list-style-type: none">• TMDG document number updated in Table 2-1 <p>Chapter 4, "System Memory Interface Design Guidelines"</p> <ul style="list-style-type: none">• Table 4-1, Table 4-7, Table 4-9, Table 4-10, Table 4-13, Table 4-16, Table 4-17 - The speed bin increased to 2666 MT/s <p>Chapter 19, "Universal Serial Bus 2.0 Design Guidelines"</p> <ul style="list-style-type: none">• CFL H PCH or CFL-S PCH changed to CNP PCH-H.• Topology diagrams are cleaned.• ESD diode recommendation is added in Flex and Docking Topology. <p>Chapter 22, "MIPI SoundWire* Interface Design Guidelines"</p> <ul style="list-style-type: none">• Updated Table 22-3 with Resistor minimum and Maximum distance <p>Chapter 42, "Wireless Connectivity Integration (CNVi) Design Considerations"</p> <ul style="list-style-type: none">• Requirements for a slow clock (32 KHz) removed from Section 42.3.1.5• Additional note on reference planes added in Section 42.5.1• Cosmetic corrections applied to CNVio Device Down Topology Values table.• Updated Section 42.5.5.1 with separate topology diagrams and routing guidelines table for DT and RSP signals.• Figure 42-8, Figure 42-9 updated with external pull-up resistor of 20K Ohm in the block diagrams.• Table 42-6 - the XTAL_SEL2 description is updated with 20K Ohm pull-up resistor details.	August 2017



Document Number	Revision Number	Description	Revision Date
571391	1.5	<p>Chapter 2, "Stack-Up and PCB Considerations"</p> <ul style="list-style-type: none">• Updated Table 2-9 to Table 2-13 <p>Chapter 3, "General Differential Design Guidelines"</p> <ul style="list-style-type: none">• Updated Figure 3-32 <p>Chapter 4, "System Memory Interface Design Guidelines"</p> <ul style="list-style-type: none">• Table 4-1 - 2666 is now supported for DDP x16• Table 4-10 - Both SDP and DDP supports 2666 MT/s• Table 4-11 - RCOMP[0] value fixed <p>Chapter 9, "Direct Media Interface Design Guidelines"</p> <ul style="list-style-type: none">• Added Notes in Table 9-1 and Table 9-2 <p>Chapter 30, "Serial Peripheral Interface (SPI0) Flash Design Guidelines"</p> <ul style="list-style-type: none">• Added Note in Section 30.2.1 and Section 30.2.3 <p>Chapter 32, "Legacy Audio Interface Design Guidelines"</p> <ul style="list-style-type: none">• Updated Table 32-2, Table 32-3, and Table 32-6 table notes and references• Updated Table 32-3 PCH Buffer values• Added details on Table 32-3 to clarify use of RS2 and RS3 for DMIC usage <p>Chapter 45, "Platform Power Sequencing Specification"</p> <ul style="list-style-type: none">• Updated tPLT15/tCPU21 and added tPLT20	January 2018
571391	1.8	<p>Chapter 2, "Stack-Up and PCB Considerations"</p> <ul style="list-style-type: none">• Updated CFL Signal Integrity Tool Suite Document number <p>Chapter 20, "USB Type-C"</p> <ul style="list-style-type: none">• Updated Figure 20-6 and Figure 20-7 <p>Chapter 21, "PCH Signal Glitch Free Implementation Requirements"</p> <ul style="list-style-type: none">• Updated Table 21-3 <p>Chapter 42, "Wireless Connectivity Integration (CNVi) Design Considerations"</p> <ul style="list-style-type: none">• Updated Figure 42-19• Updated CFL Signal Integrity Tool Suite Document number <p>Chapter 50, "Processor and PCH Power Integrity Recommendations"</p> <ul style="list-style-type: none">• Added Table 50-5 <p>Chapter 51, "Power Delivery"</p> <ul style="list-style-type: none">• Updated Table 51-7 <p>Added Chapter 52, "Flexible Instrumented Platform (FIP) Design"</p>	May 2018
571391	2.0	<p>Chapter 45, "Platform Power Sequencing Specification"</p> <ul style="list-style-type: none">• Table 45-5<ul style="list-style-type: none">— Updated tPCH01 description— Added notes - 47 and 48 <p>Chapter 50, "Processor and PCH Power Integrity Recommendations"</p> <ul style="list-style-type: none">• Added Figure 50-2	October 2019
571391	2.1	<p>Chapter 4, "System Memory Interface Design Guidelines"</p> <ul style="list-style-type: none">• Table 4-1 - Updated frequency of SODIMM 2DPC/1DPC with/without ECC topology	August 2020
571391	2.2	<p>Chapter 23, "I²C* Interface Design Guidelines"</p> <ul style="list-style-type: none">• Updated section 23.1.2.1 General Design Considerations• Updated table 23-5. Bus Capacitance / Pull-Up and Current Assist Strength Settings	September 2020
571391	2.3	<p>Chapter 9, "Direct Media Interface Design Guidelines"</p> <ul style="list-style-type: none">• Added Table 9-2	December 2020



1 Introduction

This Design Guide provides motherboard implementation recommendations for the Coffee Lake platform, based on the Coffee Lake processor. This document includes design guides for platforms.

The Coffee Lake platform consists of CFL H 2-Chip Platform Series and CFL S 2-Chip Platform Series. Cannon Lake PCH, also known as CNP PCH, refers to the PCH portion of the Coffee Lake platform. The Coffee Lake H and S 2-Chip platform consists of CFL processor package with Cannon Lake PCH package.

CFL H will be based out of CNP PCH H.

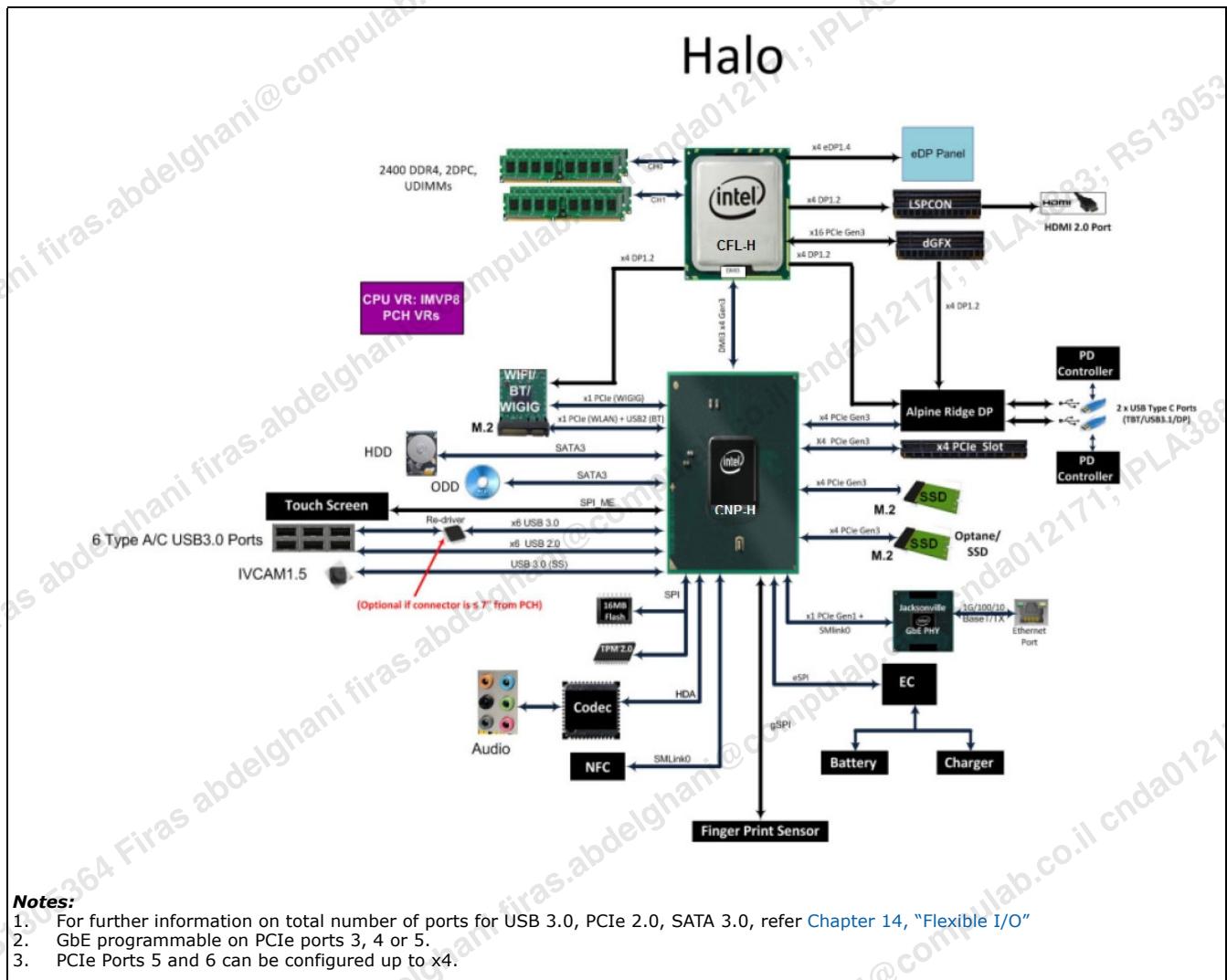
CNP PCH-H can be paired with CFL S CPU

Note: For CFL platform PCH sku details, refer to *Cannon Lake Platform Controller Hub-H (PCH-H) – External Design Specification (EDS)* (# 566439).

Note: For Mehlow Server Platform Design Guide (PDG), refer to (# 571518).

The Coffee Lake Platform Design Guide has been developed to ensure maximum flexibility for board designers while reducing the risk of board related issues. Design recommendations are based on Intel's simulations and lab experience and are strongly recommended, if not necessary, to meet the timing and signal quality specifications. Design recommendations are based on the reference platforms designed by Intel. They should be used as an example but may not be applicable to particular designs.

The guidelines recommended in this document are based on experience, simulation, and preliminary validation work done at Intel while developing the Coffee Lake processor-based platform. This work is ongoing, and these recommendations are subject to change. Metric units are used in some sections in addition to the standard use of U.S. customary system of units (USCS). If there is a discrepancy between the metric and USCS units, assume the USCS unit is most accurate. The conversion factor used is 1 inch (1000 mils) = 25.4 mm.

**Figure 1-1. Coffee Lake H Platform Block Diagram****Table 1-1. CFL H Platform Windows* OS Support**

H	OS Support
OS POR	Windows* 10
Consumer (ME 1.5M)	Yes
Corporate (ME 5M)	Yes



1.1

Terminology

Term	Description
AOAC	Always On, Always Connected
DPTF	Dynamic Platform and Thermal Framework; includes configurable TDP and Low Power Mode.
DPPM	Dynamic Power Performance Management
MCP	Multi-Chip Package. A single package with multiple dies (processor and PCH) with interconnects between them, which fits into a single socket.

1.2

Reference Documents

Document	Document Number
Coffee Lake Processor Families External Design Specification Volume 1 of 2	570805
Coffee Lake Processor Families External Design Specification Volume 2 of 2	570806
Coffee Lake Processor High Speed Interface Spice models	570865
Coffee Lake H Processor Line BGA Package Ballout Mechanical Specification	570699
Coffee Lake Turbo and Thermal Power Management Guide for Intel Core-based Processors	571040
Coffee Lake Platform Mobile Thermal and Mechanical Design Guide	571296

§ §



2 Stack-Up and PCB Considerations

If the guidelines are not followed, complete signal integrity and timing simulations for each design is required. If the guidelines are followed, simulate critical signals to ensure proper signal integrity and flight timing.

Refer to *Coffee Lake Platform Mobile Thermal Mechanical Design Guide (TMDG)* for thermal and mechanical design guidelines, such as component PCB pad design recommendations and NCTF corner ball routing guidelines.

Note:

Metric units are used in some sections in addition to the standard use of U.S. customary system of units (USCS). If there is a discrepancy between the metric and USCS units, assume the USCS unit is most accurate. The conversion factor used is 1 inch (1000 mils) = 25.4 mm.

Table 2-1. Stack-Up and PCB Considerations Reference Documents

Title	Location / Document Number
<i>Coffee Lake Platform Mobile Thermal Mechanical Design Guide</i>	566757

2.1 Printed Circuit Board Considerations

Several layer count configurations may be implemented on the platform, provided the trace geometries of the individual microstrip and stripline routing layers fall within the parameter value ranges and the impedance specifications are met. It is important to note that variations in the stack-up of a motherboard, such as changes in the dielectric height, trace widths, and spacing, can impact the impedance, loss, and jitter characteristics of all the interfaces. Such changes may either be intentional or the result of variations encountered during the PCB manufacturing process. In either case, they must be properly considered when designing interconnects.

The following diagrams and tables depict the typical values and tolerances Intel assumes for microstrip, stripline, and dual-stripline routing layers for single-ended and differential signals.

- Design tolerances account for adjustments intentionally included in their design.
- Material tolerances account for any natural variation in the materials being used.
- Manufacturing tolerance considers variations that may occur during the manufacturing process.
- Use the design tolerance to re-center stack-up impedance, but consider the manufacturing tolerance impact when comparing the chosen stack-up to the given recommendation.

The following general stack-up recommendations should be followed:

- For power and ground planes, it is preferred to use 1 oz. copper where possible.

- All high-speed signals should reference solid planes over the length of their routing and should not cross plane splits. Ground referencing is preferred.
- Reference plane stitching vias must be used in conjunction with high-speed signal layer transitions that include a reference plane change. Refer to each signal group section for more specification.
- High-speed routing on external layers should be minimized to avoid the possibility of EMI. Routing on external layers also introduces different delays compared to internal layers. In general, interfaces that have length matching requirements also restrict routing for groups of signals to be on the same layer to avoid this situation.
- The parameter values for internal and external traces are the final thickness and width.
- Signals must not be routed directly under the processor cavity without at least one solid metal plane above it. Without a "shield" there could be excessive noise coupling from the package to the signal layer. This is a requirement for all motherboards.

Figure 2-1. Single-Ended Microstrip Diagram

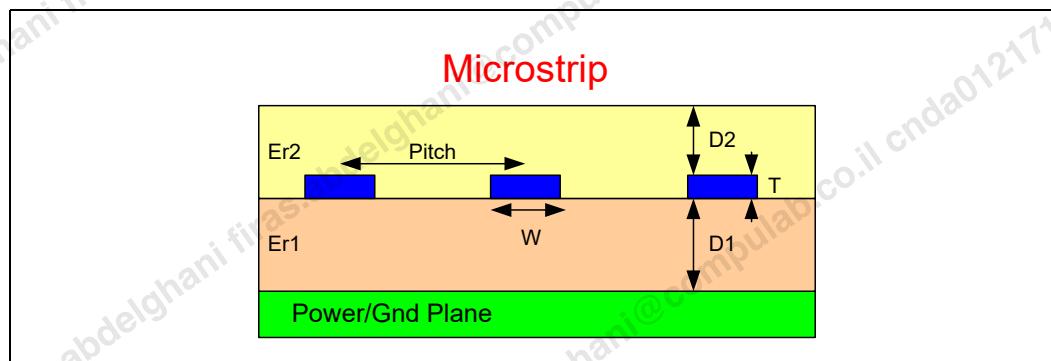
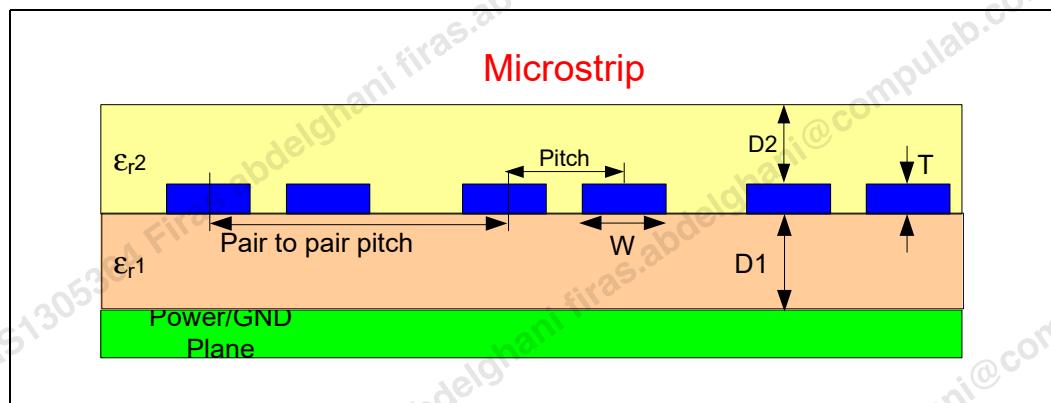


Figure 2-2. Differential-Microstrip Diagram



**Table 2-2. CFL H Type 3 PCB Stack-Up Parameter Values (Microstrip)**

Microstrip	Units	Min Value	Negative Manufacturing Tolerance	Negative Design/ Material Tolerance	Typical Value	Positive Design/ Material Tolerance	Positive Manufacturing Tolerance	Max Value
D1	mils	2	0.3	0.4	2.7	0.2	0.3	3.2
D2	mils	0.1	0.3	0.25	0.65	0.25	0.30	1.20
ϵ_{r1}	NA	3.45	0.15	0.3	3.9	0.3	0.15	4.35
ϵ_{r2}	NA	3.20	0.2	0	3.40	0	0.2	3.60
Trace Thickness (½ oz. Plated)	mils	1.3	0.28	0.32	1.9	0.32	0.28	2.5
Trace Width Top = Trace Width Bottom - 1mil Refer to Figure 2-1 and Figure 2-2 EDW=0.5								

Table 2-3. CFL H Type 4 PCB Stack-Up Parameter Values (Microstrip)

Microstrip	Units	Min Value	Negative Manufacturing Tolerance	Negative Design/ Material Tolerance	Typical Value	Positive Design/ Material Tolerance	Positive Manufacturing Tolerance	Max Value
D1	mils	1.8	0.3	0.4	2.5	0.2	0.3	3.0
D2	mils	0.1	0.3	0.25	0.65	0.25	0.30	1.20
ϵ_{r1}	NA	3.45	0.15	0.3	3.9	0.3	0.15	4.35
ϵ_{r2}	NA	3.20	0.2	0	3.40	0	0.2	3.60
Trace Thickness (1/2 oz. Plated)	mils	0.8	0.28	0.32	1.4	0.32	0.28	2.0
Trace Width Top = Trace Width Bottom - 1mil Refer to Figure 2-1 and Figure 2-2 EDW=0.5								

Table 2-4. CFL H Type 3 PCB Stack-Up Parameter Values (Dual-Stripline)

8-layer/10-layer Dual-Stripline	Units	Min Value	Negative Manufacturing Tolerance	Negative Design/ Material Tolerance	Typical Value	Positive Design/ Material Tolerance	Positive Manufacturing Tolerance	Max Value
D1	mils	3.375	0.375	0.25	4.00	0.35	0.375	4.725
D2	mils	4.375	0.375	0.25	5.00	0.35	0.375	5.725
D3	mils	3.375	0.375	0.25	4.00	0.35	0.375	4.725
ϵ_{r1}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r2}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r3}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
Trace Thickness (1/2 oz plated)	mils	0.50	0.05	0.05	0.60	0.05	0.05	0.70
Refer to Figure 2-3 and Figure 2-4 . EDW=0								

**Table 2-5. CFL H Type 4 PCB Stack-Up Parameter Values (2 x 2+ 1 Oz Dual-Stripline)**

8-layer/10-layer Dual-Stripline	Units	Min Value	Negative Manufacturing Tolerance	Negative Design/ Material Tolerance	Typical Value	Positive Design/ Material Tolerance	Positive Manufacturing Tolerance	Max Value
D1	mils	2.375	0.375	0.25	3.00	0.35	0.375	3.725
D2	mils	1.875	0.375	0.25	2.50	0.35	0.375	3.225
D3	mils	1.875	0.375	0.25	2.50	0.35	0.375	3.225
ϵ_{r1}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r2}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r3}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
Trace Thickness (1/3 oz plated)	mils	0.6	0.28	0.32	1.20	0.32	0.28	1.8
Refer to Figure 2-3 and Figure 2-4. EDW=0.25								

Note: Dual stripline of L3/L4 and L7/L8 has dielectric thickness of 2.5 mils, signal parallelism should be avoided to eliminate potential crosstalk between L3/L4 and L7/L8.

Table 2-6. CFL H Type 4 PCB Stack-Up Parameter Values for (2 x 2+ 0.5 Oz Dual-Stripline)

8-layer/10-layer Dual-Stripline	Units	Min Value	Negative Manufacturing Tolerance	Negative Design/ Material Tolerance	Typical Value	Positive Design/ Material Tolerance	Positive Manufacturing Tolerance	Max Value
D1	mils	1.875	0.375	0.25	2.50	0.35	0.375	3.225
D2	mils	1.875	0.375	0.25	2.50	0.35	0.375	3.225
D3	mils	2.375	0.375	0.25	3.00	0.35	0.375	3.725
ϵ_{r1}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r2}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r3}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
Trace Thickness (1/3 oz plated)	mils	0.5	0.05	0.50	0.60	0.050	0.050	0.70
Refer to Figure 2-3 and Figure 2-4. EDW=0								

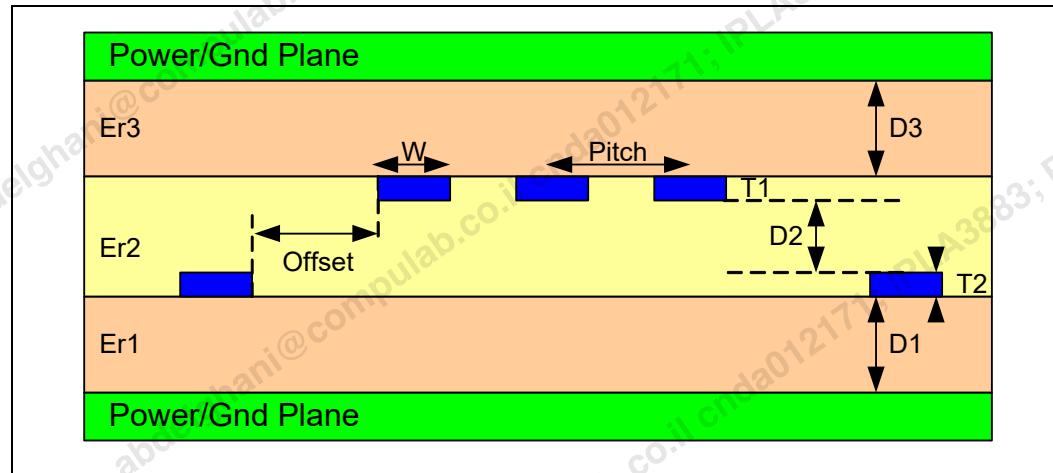
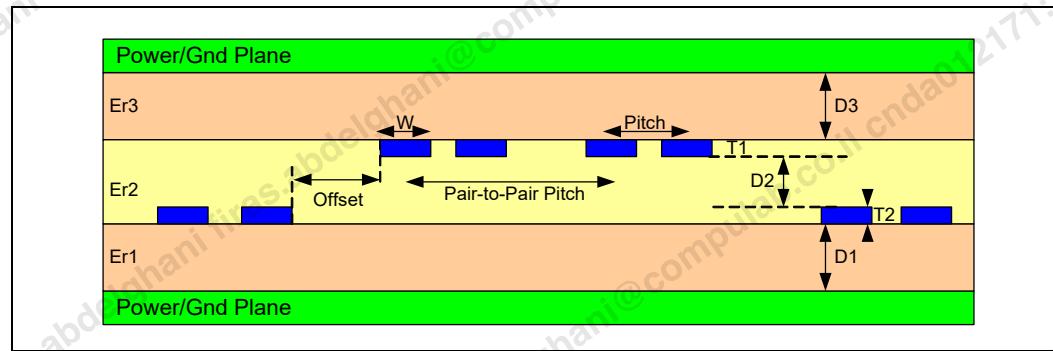
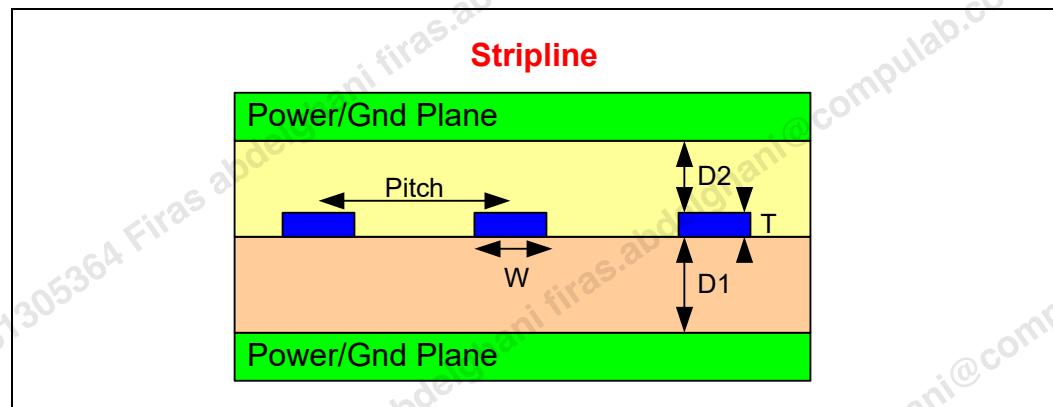
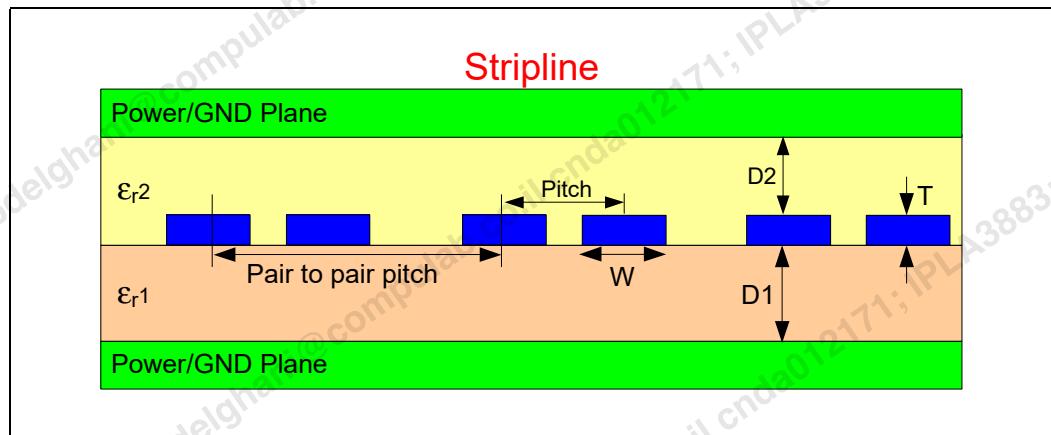
Figure 2-3. Single-Ended Dual-Stripline Diagram**Figure 2-4. Differential Dual-Stripline Diagram****Figure 2-5. Single-Ended Stripline Diagram**

Figure 2-6. Differential Stripline Diagram

Table 2-7. CFL H Type 4 PCB Stack-Up Parameter Values (Stripline 1-x-1/1-x-1+)

Stripline	Units	Min Value	Negative Manufacturing Tolerance	Negative Design/ Material Tolerance	Typical Value	Positive Design/ Material Tolerance	Positive Manufacturing Tolerance	Max Value
D1	mils	3.375	0.375	0.25	4	0.35	0.375	4.725
D2	mils	4.375	0.375	0.25	5.0	0.35	0.375	5.725
ϵ_{r1}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r2}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
Trace Thickness (0.5 oz Plated)	mils	0.5	0.05	0.05	0.6	0.05	0.05	0.7
Refer to Figure 2-5 and Figure 2-6. EDW=0								

Table 2-8. CFL H Type 3 PCB Stack-Up Parameter Values (Stripline 8/10 Layer)

Stripline	Units	Min Value	Negative Manufacturing Tolerance	Negative Design/ Material Tolerance	Typical Value	Positive Design/ Material Tolerance	Positive Manufacturing Tolerance	Max Value
D1	mils	3.375	0.375	0.25	4.0	0.35	0.375	4.725
D2	mils	4.375	0.375	0.25	5.0	0.35	0.375	5.725
ϵ_{r1}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
ϵ_{r2}	NA	3.70	0.15	0.275	4.125	0.275	0.15	4.55
Trace Thickness (1/2 oz Plated)	mils	0.5	0.05	0.05	0.6	0.05	0.05	0.7
Refer to Figure 2-5 and Figure 2-6. EDW=0								

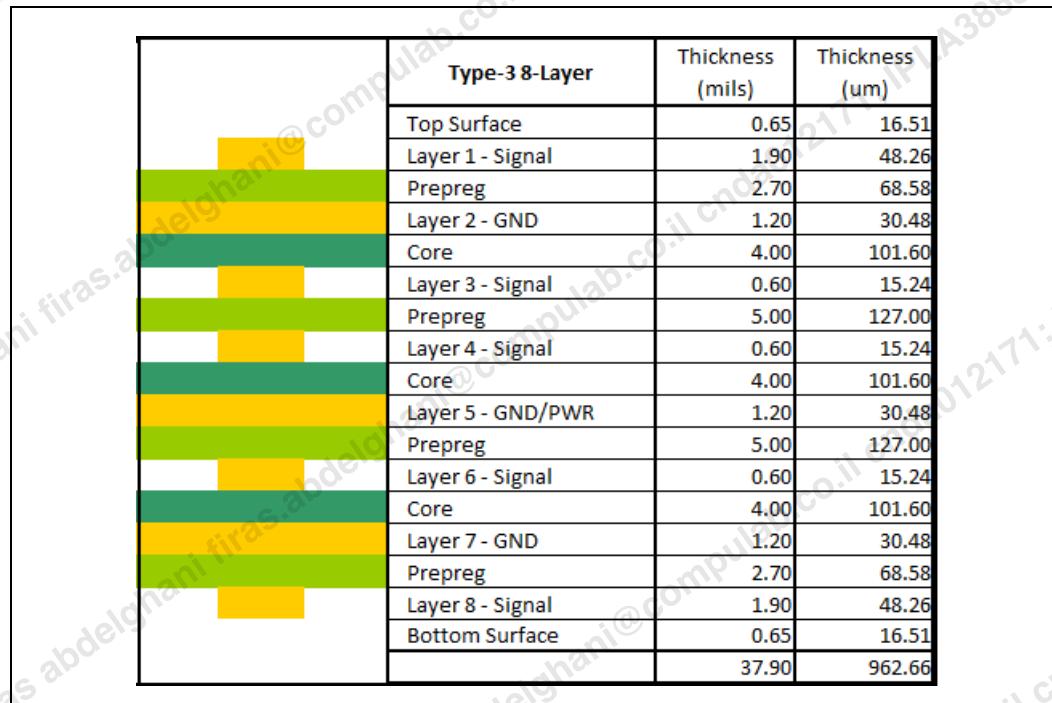


2.2

Generalized 8-Layer Motherboard Example

An example of a typical 8-layer type 3 PCB stack-up with stripline routing is shown in [Figure 2-8](#). An example of a typical 8-layer type 3 PCB stack-up with dual-stripline routing is shown in [Figure 2-7](#). These sample stack-ups are provided as a reference only.

Figure 2-7. CFL H Dual-Stripline 8-Layer Type 3 PCB Stack-Up



Type-3 8-Layer	Thickness (mils)	Thickness (um)
Top Surface	0.65	16.51
Layer 1 - Signal	1.90	48.26
Prepreg	2.70	68.58
Layer 2 - GND	1.20	30.48
Core	4.00	101.60
Layer 3 - Signal	0.60	15.24
Prepreg	5.00	127.00
Layer 4 - Signal	0.60	15.24
Core	4.00	101.60
Layer 5 - GND/PWR	1.20	30.48
Prepreg	5.00	127.00
Layer 6 - Signal	0.60	15.24
Core	4.00	101.60
Layer 7 - GND	1.20	30.48
Prepreg	2.70	68.58
Layer 8 - Signal	1.90	48.26
Bottom Surface	0.65	16.51
	37.90	962.66

Note: If there are concerns with warpage due to unbalanced center core, use 1/2 oz copper on L5.

2.3

Generalized 10-Layer Motherboard Example

An example of a typical, 10-layer type 3 PCB stack-up is shown in [Figure 2-8](#). These sample stack-ups are provided as a reference when routing the different interfaces.

Figure 2-8. CFL H 10 Layer Type 3 PCB Stack-Up



Type-3 10-Layer	Thickness (mils)	Thickness (um)
Top Surface	0.65	16.51
Layer 1 - Signal	1.90	48.26
Prepreg	2.70	68.58
Layer 2 - GND	1.20	30.48
Core	4.00	101.60
Layer 3 - Signal	0.60	15.24
Prepreg	5.00	127.00
Layer 4 - Signal	0.60	15.24
Core	4.00	101.60
Layer 5 - GND/PWR	1.20	30.48
Prepreg	3.00	76.20
Layer 6 - GND/PWR	1.20	30.48
Core	4.00	101.60
Layer 7 - Signal	0.60	15.24
Prepreg	5.00	127.00
Layer 8 - Signal	0.60	15.24
Core	4.00	101.60
Layer 9 - GND	1.20	30.48
Prepreg	2.70	68.58
Layer 10 - Signal	1.90	48.26
Bottom Surface	0.65	16.51
	46.70	1186.18

An example of a typical, 10-layer type 4 PCB stack-up is shown in [Figure 2-9](#). These sample stack-ups are provided as a reference when routing the different interfaces.

Dual stripline of L3/L4 and L7/L8 has dielectric thickness of 2.5 mils, signal parallelism should be avoided to eliminate potential crosstalk between L3/L4 and L7/L8.



Figure 2-9. CFL H 10-Layer Type 4 PCB Stack-Up 2-x-2+ (L5, L6 is 1 oz. copper)

2-x-2+ 10-Layer (L5, L6 - 1Oz Cu)	Thickness (mils)	Thickness (um)
Top Surface	0.65	16.51
Layer 1 - Signal	1.40	35.56
Prepreg	2.50	63.50
Layer 2 - GND	1.20	30.48
Prepreg	2.50	63.50
Layer 3 - Signal	1.20	30.48
Prepreg	2.50	63.50
Layer 4 - Signal	0.60	15.24
Core	3.00	76.20
Layer 5 - GND/PWR	1.20	30.48
Prepreg	2.50	63.50
Layer 6 - GND/PWR	1.20	30.48
Core	3.00	76.20
Layer 7 - Signal	0.60	15.24
Prepreg	2.50	63.50
Layer 8 - Signal	1.20	30.48
Prepreg	2.50	63.50
Layer 9 - GND	1.20	30.48
Prepreg	2.50	63.50
Layer 10 - Signal	1.40	35.56
Bottom Surface	0.65	16.51
	36.00	914.40

Dual stripline of L3/L4 and L7/L8 has dielectric thickness of 2.5 mils, signal parallelism should be avoided to eliminate potential crosstalk between L3/L4 and L7/L8.

Figure 2-10. CFL H 10-Layer Type 4 PCB Stack-Up 1-x-1

1-x-1 10-Layer	Thickness (mils)	Thickness (um)
Top Surface	0.65	16.51
Layer 1 - Signal	1.40	35.56
Prepreg	2.50	63.50
Layer 2 - GND	1.20	30.48
Core	4.00	101.60
Layer 3 - Signal	0.60	15.24
Prepreg	5.00	127.00
Layer 4 - Signal	0.60	15.24
Core	4.00	101.60
Layer 5 - GND/PWR	1.20	30.48
Prepreg	3.00	76.20
Layer 6 - GND/PWR	1.20	30.48
Core	4.00	101.60
Layer 7 - Signal	0.60	15.24
Prepreg	5.00	127.00
Layer 8 - Signal	0.60	15.24
Core	4.00	101.60
Layer 9 - GND	1.20	30.48
Prepreg	2.50	63.50
Layer 10 - Signal	1.40	35.56
Bottom Surface	0.65	16.51
	45.30	1150.62



2.4 Single-Ended and Differential-Impedance Transmission Line Specifications

2.4.1 Breakout Geometries

Breakout topologies are mainly decided by package ballout patterns and pitches. So similar geometries may be used for various stack-ups. Refer to interface chapters for the breakout maximum length allowed and signals not listed.

Table 2-9. CFL H Breakout Geometries for Type 3 and Type 4 PCB

I/O Interfaces	Stack-Up	Units	Trace Width	Minimum Trace Spacing	Minimum Pair-to-Equivalent Pair Spacing ¹	Minimum Pair-to-Non-Equivalent Pair Spacing ¹
DP/HDMI/eDP/PEG/DMI	MS	mils	3	3	9	15
	SL/DSL	mils	3	3.5	10	15
SATA/PCH PCIe/Platform Clocks/USB3.x	MS	mils	3.5	4.0	8	15
	SL/DSL	mils	3	3.5	8	15
USB 2.0	MS	mils	3.5	4.0	8	15
	SL/DSL	mils	3	3.5	8	15
UART/SDIO/I ² C/SPI	MS	mils	3	3.5	NA	NA
	SL/DSL	mils	3	3.5	NA	NA
Others ²	MS	mils	4.0	4.0	NA	NA
	SL/DSL	mils	3	3.5	NA	NA

Notes:

- Equivalent pairs mean both pairs have equal swing and signal propagation direction. Non-equivalent pairs mean both pairs have different swing or propagation direction. Signal within the same interface and direction is considered as equivalent pair. Example DDI1 and DDI2 are non-equivalent. When different interface signal routed side by side, always refer to the larger spacing requirement.
- Other refers to legacy signals which are not listed in the table, that is, low speed non-critical signals.
- MS refers to microstrip; SL refers to stripline; DSL refers to dual stripline

2.4.2 Routing Geometries

The following tables list examples of single-ended and differential impedances specified for each interface. The microstrip single-ended impedance and differential impedance tolerance is $\pm 15\%$. The stripline and dual-stripline single-ended impedance and differential impedance tolerance is $\pm 10\%$ for type 3 PCB, $\pm 12\%$ for type 4 PCB.

Note:

The table notes below apply to the following four tables.

- For Type 4, trace width recommended is 4mils to achieve the target impedance.
- For differential interfaces, Z_0 is listed as a reference to provide a complete picture of electrical performance. There is no requirement for PCB vendors to measure this impedance.
- All width/spacing/ K_b values are given for reference based on reference stackup. In case of any change in stack up, these values need to be recalculated and priority should be given to meet Z values.



4. Refer to Memory Chapter for all routing geometries and impedance recommendations.
5. Equivalent pairs mean both pairs have equal swing and signal propagation direction. Non-equivalent pairs mean both pairs have different swing or propagation direction. Signal within the same interface and direction is considered as equivalent pair. Example DDI1 and DDI2 are non-equivalent. When different interface signal routed side by side, always refer to the larger spacing requirement.

Table 2-10. CFL H Microstrip Routing Geometries for Type 3 & Type 4 PCB

I/O Interfaces	Electrical Target			Layout Geometries				
	Target Zo (Ω)	Kb (%)	Attenuation	Units	Trace Width	Intra pair Trace Spacing	Minimum Pair-to-Equivalent Pair Spacing (Note 5)	Minimum Pair-to-Non-Equivalent Pair Spacing (Note 5)
Differential Clock	85	0.37	-0.27	mils	3.5 ¹	4.0	12.0	15.0
DP/eDP/HDMI/PCIe/USB3.1 Gen1/SATA/USB2/CNVi DPHY	85	0.37	-0.27	mils	3.5 ¹	4.0	12.0	12.0
USB 3.1 Gen2	80	0.17	-0.96	mils	5.0	5.0	18.0	20.0
Single ended IO (clock, except SoundWire Star Topology M1 Segment) / SVID	50	1.23	-0.25	mils	4.0	N/A	15.0	15.0
Single ended IO (non clock, except SoundWire Star Topology M1 Segment) / PCH Sideband		5.98	-0.26	mils			5.0	5.0
CPU asynchronous and Sideband signals		1.77	-0.25	mils			12	12
PECI		0.90	-0.25	mils			18	18
SD card/ SPI0 flash (non-clock)		2.36	-0.25	mils			10	10
XTAL / RTC		0.75	-0.25	mils			20	70
CLKIN_LPC		N/A	N/A	mils			N/A	70
SoundWire Star Topology (M1 Segment for clock)	35	1.68	-0.25	mils	8.0	N/A	12.0	24.0
SoundWire Star Topology (M1 Segment for non clock)	35	1.68	-0.25	mils	8.0	N/A	12.0	16.0

**Table 2-11. CFL H Stripline routing geometry for Type-3 PCB**

I/O Interfaces	Electrical Target			Layout Geometries				
	Target Zo (Ω)	Kb (%)	Attenuation	Units	Trace Width	Intra pair Trace Spacing	Minimum Pair-to-Equivalent Pair Spacing (Note 5)	Minimum Pair-to-Non-Equivalent Pair Spacing (Note 5)
Differential Clock	85	0.015	-0.25	mils	4.0	4.0	12.0	15.0
DP/eDP/HDMI/PCIe/USB3.1 Gen1/SATA/USB2/CNVi DPHY	85	0.07	-0.25	mils	4.0	4.0	12.0	12.0
USB 3.1 Gen2	80	0.03	-1.04	mils	5.0	5.0	18.0	20.0
Single ended IO (clock, except SoundWire Star Topology M1 Segment) / SVID	50	0.16	-0.25	mils	4.0	N/A	15.0	15.0
Single ended IO (non clock, except SoundWire Star Topology M1 Segment) / PCH Sideband		2.22	-0.26	mils			5.0	5.0
CPU asynchronous and Sideband signals		0.42	-0.25	mils			12	12
PECI		0.16	-0.25	mils			18	18
SD card/ SPIO flash (non-clock)		2.36	-0.25	mils			10	10
XTAL / RTC		0.75	-0.25	mils			20	70
CLKIN_LPC		N/A	N/A	mils			N/A	70
SoundWire Star Topology (M1 Segment for clock)	35	1.68	-0.25	mils	7.0	N/A	12.0	24.0
SoundWire Star Topology (M1 Segment for non clock)	35	1.68	-0.25	mils	7.0	N/A	12.0	16.0

Table 2-12. CFL H Dual Stripline routing geometry for Type-3 PCB (Sheet 1 of 2)

I/O Interfaces	Electrical Target			Layout Geometries				
	Target Zo (Ω)	Kb (%)	Attenuation	Units	Trace Width	Intra pair Trace Spacing	Minimum Pair-to-Equivalent Pair Spacing (Note 5)	Minimum Pair-to-Non-Equivalent Pair Spacing (Note 5)
Differential Clock	85	0.080	-0.25	mils	4.5	4.0	12.0	15.0
DP/eDP/HDMI/PCIe/USB3.1 Gen1/SATA/USB2/CNVi DPHY	85	0.44	-0.25	mils	4.5	4.0	12.0	12.0
USB 3.1 Gen2	80	0.03	-1.04	mils	5.5	5.0	18.0	20.0

**Table 2-12. CFL H Dual Stripline routing geometry for Type-3 PCB (Sheet 2 of 2)**

I/O Interfaces	Electrical Target			Layout Geometries				
	Target Zo (Ω)	Kb (%)	Attenuation	Units	Trace Width	Intra pair Trace Spacing	Minimum Pair-to-Equivalent Pair Spacing (Note 5)	Minimum Pair-to-Non-Equivalent Pair Spacing (Note 5)
Single ended IO (clock, except SoundWire Star Topology M1 Segment) / SVID	50	0.63	-0.25	mils	4.5	N/A	15.0	15.0
Single ended IO (non clock, except SoundWire Star Topology M1 Segment) / PCH Sideband		2.22	-0.26	mils			5.0	5.0
CPU asynchronous and Sideband signals		0.42	-0.25	mils			12	12
PECI		0.16	-0.25	mils			18	18
SD card/ SPIO flash (non-clock)		2.36	-0.25	mils			10	10
XTAL / RTC		0.75	-0.25	mils			20	70
CLKIN_LPC		N/A	N/A	mils			N/A	70
SoundWire Star Topology (M1 Segment for clock)	35	1.68	-0.25	mils	8.5	N/A	12.0	24.0
SoundWire Star Topology (M1 Segment for non clock)	35	1.68	-0.25	mils	8.5	N/A	12.0	16.0

Table 2-13. CFL H Dual Stripline routing geometry for Type-4 (2-x-2+ 1Oz.)PCB (Sheet 1 of 2)

I/O Interfaces	Electrical Target			Layout Geometries				
	Target Zo (Ω)	Kb (%)	Attenuation	Units	Trace Width	Intra pair Trace Spacing	Minimum Pair-to-Equivalent Pair Spacing (Note 5)	Minimum Pair-to-Non-Equivalent Pair Spacing (Note 5)
Differential Clock	85	0.080	-0.25	mils	2.5	3.5	12.0	15.0
DP/eDP/HDMI/PCIe/USB3.1 Gen1/SATA/USB2/CNVi DPHY	85	0.44	-0.25	mils	2.5	3.5	12.0	12.0
USB 3.1 Gen2	80	0.03	-1.04	mils	3.0	3.5	18.0	20.0



Table 2-13. CFL H Dual Stripline routing geometry for Type-4 (2-x-2+ 1Oz.)PCB (Sheet 2 of 2)

I/O Interfaces	Electrical Target			Layout Geometries				
	Target Zo (Ω)	Kb (%)	Attenuation	Units	Trace Width	Intra pair Trace Spacing	Minimum Pair-to-Equivalent Pair Spacing (Note 5)	Minimum Pair-to-Non-Equivalent Pair Spacing (Note 5)
Single ended IO (clock, except SoundWire Star Topology M1 Segment) / SVID	50	0.63	-0.25	mils	4.5	N/A	15.0	15.0
Single ended IO (non clock, except SoundWire Star Topology M1 Segment) / PCH Sideband		2.22	-0.26	mils			5.0	5.0
CPU asynchronous and Sideband signals		0.42	-0.25	mils			12	12
PECI		0.16	-0.25	mils			18	18
SD card/ SPIO flash (non-clock)		2.36	-0.25	mils			10	10
XTAL / RTC		0.75	-0.25	mils			20	70
CLKIN_LPC		N/A	N/A	mils			N/A	70
SoundWire Star Topology (M1 Segment for clock)	35	1.68	-0.25	mils	6.0	N/A	12.0	24.0
SoundWire Star Topology (M1 Segment for non clock)	35	1.68	-0.25	mils			12.0	16.0

2.5

Low Halogen Flame Retardant Stack-Up Considerations

FR4 epoxy has been used in the construction of PCBs for decades. Consequently, its electrical properties, which are influenced by brominated flame retardants integrated into the molecular structure of the resin, have been studied extensively. As an environmentally friendly alternative to the halogenated flame retardants in FR4, several new low halogen (LH) formulations were developed by different material suppliers. Unfortunately, each new formulation has a unique electrical performance that differs from FR4. This leads to the current problem: The critical electrical properties of many LH dielectrics currently on the market make it difficult to design high-speed busses without increasing the cost of the system. The range of supported Er values therefore limits the amount of cost added.

The most apparent problem lies with the increased permittivity of the LH dielectric materials compared to FR4. Measurements show that several LH PCB materials on the market can have permittivity values around 5 at 1 GHz (using 1080 glass), while FR4 has permittivity values in the 3.6 - 3.9 range. Increased permittivity requires thicker dielectric layers to achieve the equivalent impedance as FR4. In turn, the thicker



dielectric layers lead to an increase in crosstalk which reduces bus performance. If the trace-trace spacing and line widths remain constant (consequently board area consumed remains constant), and the dielectric thickness is adjusted to maintain constant characteristic impedance, the bus performance is reduced for high permittivity values due to increased crosstalk.

Conventional means of reducing crosstalk is to isolate traces as much as practical to reduce the electromagnetic coupling of energy. Unfortunately, modern motherboard designs are often real-estate constrained, requiring extra layers (and therefore cost) to provide additional space for crosstalk compensation when using high permittivity dielectrics.

2.5.1

Choosing a Low Halogen Material

Choosing an LH dielectric material for a specific design requires a compromise between performance and cost, especially when a single design is required to work with both LH and FR4 PCB materials. Consequently, it is impossible to define universal requirements for LH dielectrics that will be adequate for all products on the market. Generally speaking however, the dielectric materials used to design printed circuit boards (PCBs) with high-speed digital interfaces perform better with low permittivity and low losses. Low permitivity tends to reduce crosstalk noise for given impedance and low loss tangents reduce signal attenuation.

2.5.2

Electrical Limits of Low Halogen Material Properties

Although it is impossible to define electrical limits to universally select "good" materials versus "bad" materials because each design is unique in its implementation, general limits can be chosen that will be adequate for most applications. Simulations were performed on several high-speed buses and validation platforms were built to help identify electrical limits of LH materials that will help ensure:

- Adequate bus performance;
- Interchangeability between FR4 and LH material.

The layout constraints listed in this document have been designed to function with both standard FR4 and LH materials if the electrical properties of the LH materials fall within the envelope defined by the table below.

Table 2-14. Electrical Limits of LH Material Properties

Parameter	Approximate LH Electrical Limits	Environmental Condition
Permittivity (Er)	<4.2 (1080, RC~61%) <4.3 (RC~50%) <4.5 (2116, RC~45%)	Any environmental conditions
Loss Tangent ($\tan\delta$)	<0.018 (1080, RC~61%) <0.014 (1080, RC~50%) <0.013 (2116, RC~45%)	50% RH & 75°F
Moisture Impact on Loss ($\tan\delta$)	<0.024(1080, RC~61%) <0.019(RC=50%) <0.017 (2116, RC~45%)	95% RH & 95°F

Note:

Approximate limits of desired electrical performance of LH dielectric materials; RC =% Resin Content, RH = Relative Humidity; 1080 stack-ups have between ~ 60-65% resin content depending on the layer thickness; Limits established using buses implemented on 1080 material. 2116 (RC=45%) and RC=50% limits extrapolated from the 1080



data points using the volume ratio of resin to glass and average values of resin density, glass density, glass permittivity, glass tan and glass weight basis.

Although the limits listed in the table above are generally lower performance than standard FR4, simulated and measured data indicate that they are sufficient to ensure proper functionality of the buses listed in this design guide. Since the volume of LH materials on the market is small compared to FR4, the performance envelope was made as large as practical to maximize the number of LH materials that comply without significantly sacrificing signal integrity. [Table 2-14](#) does not ensure equal performance to FR4. However, if the limits are adhered to, then the risk of signal integrity problems due to the LH material is greatly reduced. Intel bases signal integrity analysis and validation on these ranges.

Designers should also ensure the LH dielectric materials chosen meet all applicable thermal, mechanical and UL flammability requirements.

2.6 Reference Planes

Reference all signal routing layers to a solid ground plane that is continuous over the length of the interconnect. Specific requirements may be defined within the interface design guideline chapters.

Using a power layer as a reference plane is allowed if the power layer is low noise and there is proper decoupling stitching at reference planes transitions to ensure high frequency return path continuity. However, this should only be considered as the secondary reference plane on internal layers where a solid continuous ground reference is already present. Even in this case the power plane must be low noise due to the possibility of noise being coupled into the associated signal planes.

Route noisy power planes on the same layers as signals to minimize fringe coupling by proper spacing separation.

2.7 Type 4 PCB Vias

2.7.1 Plated Through Hole, Buried Via, and Microvia Dimensions

Various combinations of plated through hole (PTH), buried via, and microvia dimensions when implementing type 4 PCB, as shown in the table below. Selection of one of these combinations depends on what works best for your design, and your PCB vendor. Cost and reliability are considerations in selecting one of these via combinations.

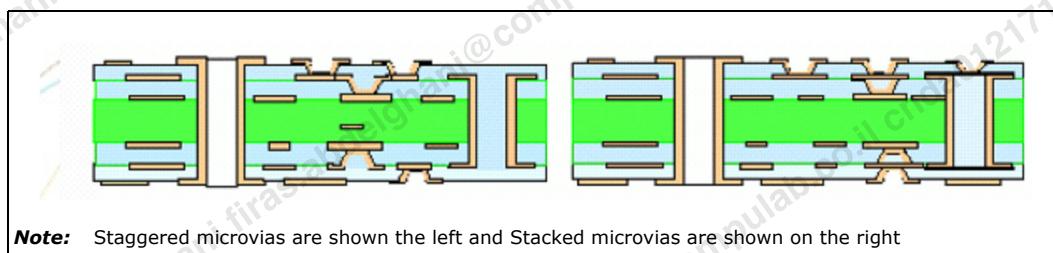
Combination #3 in the table below requires an overlap between buried via and microvia. Some PCB vendors may require the buried via to be capped. It is recommended use of this combination be reviewed with the PCB vendor, to thoroughly understand cost and reliability factors.

Table 2-15. Type 4 PCB Via Combinations

#	PTH Drill/Pad/ Antipad	Buried Via Drill/ Pad/Antipad	Microvia Drill/ Pad/Antipad	Comments
1	10/20/28	8/18/26	5/12/20	No overlap between microvia and buried via
2	10/20/28	10/20/28	4/10/18	No overlap between microvia and buried via
3	10/20/28	10/20/28	5/12/20	1 mil overlap between microvia and buried via. Consult PCB reliability rules.

2.7.2 Staggered versus Stacked Microvias

The Coffee Lake processor reference design with LPDDR3 memory down uses type 4 PCB with stacked microvias. This is especially important in the package breakout and LPDDR3 down breakout areas, where there is routing congestion and a desire to minimize voiding on the L2 ground reference plane.

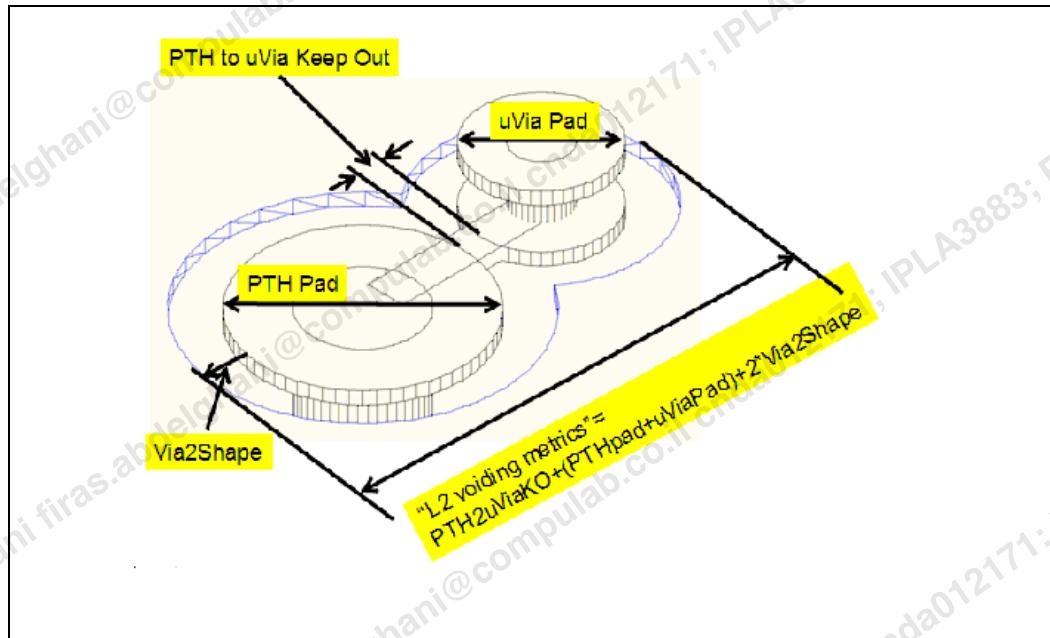
Figure 2-11. Staggered vs. Stacked Microvias


Stacked vias are used to minimize voiding of a high-speed signal's ground reference plane.

2.7.3 Buried Via to Microvia Keep-Out

In type 4 PCB, buried vias and microvia combinations create voids in the L2 GND layer. The size of these voids is primarily dependent on how large the distance is between the buried via and microvia on L2, also called the buried via to microvia keep-out.

Large keep outs can lead to significant L2 GND plane perforation and L3 signal return path discontinuities. Large keep-outs also require longer routing between vias on L2. These signals can suffer from severe impedance discontinuities as this trace segment may not find any proper reference on L1 or L3. We strongly recommend limiting the voiding on L2, by minimizing the buried via to microvia keep-out distance. If possible, use a keep-out of 0 mils.

Figure 2-12. Type 4 PCB PTH to Microvia Keep Out

2.8

Backward and Forward Coupling Coefficient Calculation

Some designs require a stack-up build that is outside of the ranges provided. In this case, compare the routing electrical characteristics versus the Intel recommendation.

Comparing the single-ended and differential-impedances is important. However, crosstalk level, which is governed by trace spacing, is not implied by the impedance target. Calculating and comparing backward coupling coefficients is recommended to choose proper trace spacing in cases where the selected stack-up varies from the Intel recommendation.

The coupling coefficients represent the source voltage percentage that is coupled to victim lines. As shown in [Figure 2-13](#), K_b is defined as the backward coupling coefficient. For backward (near-end) crosstalk, inductive and capacitive coupling are of the same polarity and the noise magnitude is not a function of trace length. The backward coupling coefficient (K_b) values can be used to decide trace spacing.

For forward (far-end) crosstalk, K_f inductive and capacitive coupling are of opposite polarity and the crosstalk magnitude (V_{fe}) is proportional to both trace length and edge rate. K_f is typically a very small value in most practical designs. Therefore, Intel has not included the K_f values in this design guide. However, the equation for calculating K_f is provided in [Figure 2-14](#), "Forward Coupling Coefficient" if the value is desired.

K_b values for all interfaces for all routing layers can be found in figures below. They were calculated assuming a nominal or typical stack-up configuration based on the values in [Table 2-10](#) through [Table 2-14](#). For single-ended interfaces, the K_b values reflect the crosstalk seen between each single-ended signal based on typical spacing. For differential interfaces, the K_b values reflect the crosstalk seen between each differential pair based on the typical pair-to-pair spacing.

Figure 2-13. Backward Coupling Coefficient

$$K_b = \frac{1}{4} \left(\frac{|C_{ij}|}{\sqrt{C_{ii}C_{jj}}} + \frac{|L_{ij}|}{\sqrt{L_{ii}L_{jj}}} \right)$$

$$V_{NE} = K_b \bullet V_0$$

Figure 2-14. Forward Coupling Coefficient

$$K_f = \frac{1}{2} \left(\frac{|C_{ij}|}{\sqrt{C_{ii}C_{jj}}} - \frac{|L_{ij}|}{\sqrt{L_{ii}L_{jj}}} \right) (L_{ii}C_{ii}L_{jj}C_{jj})^{1/4}$$

$$V_{FE} = K_f \bullet Length * \frac{dV}{dt}$$

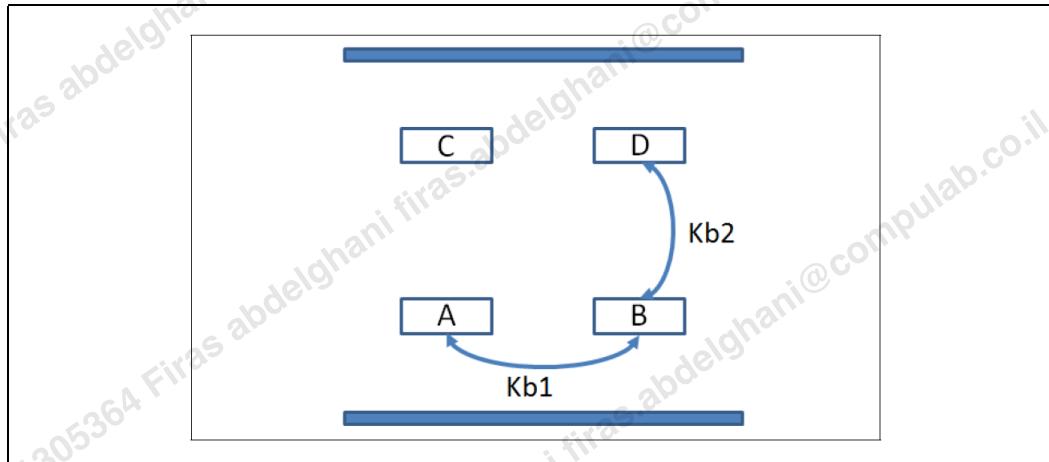
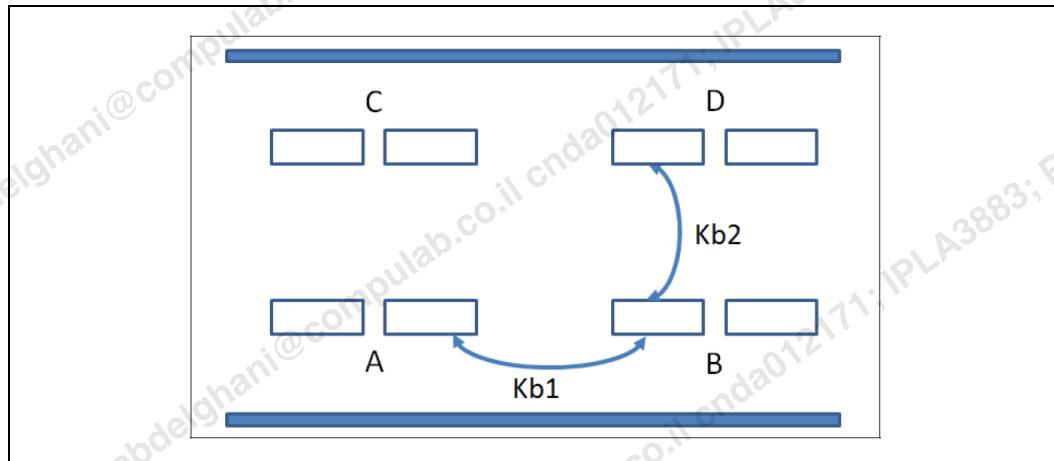
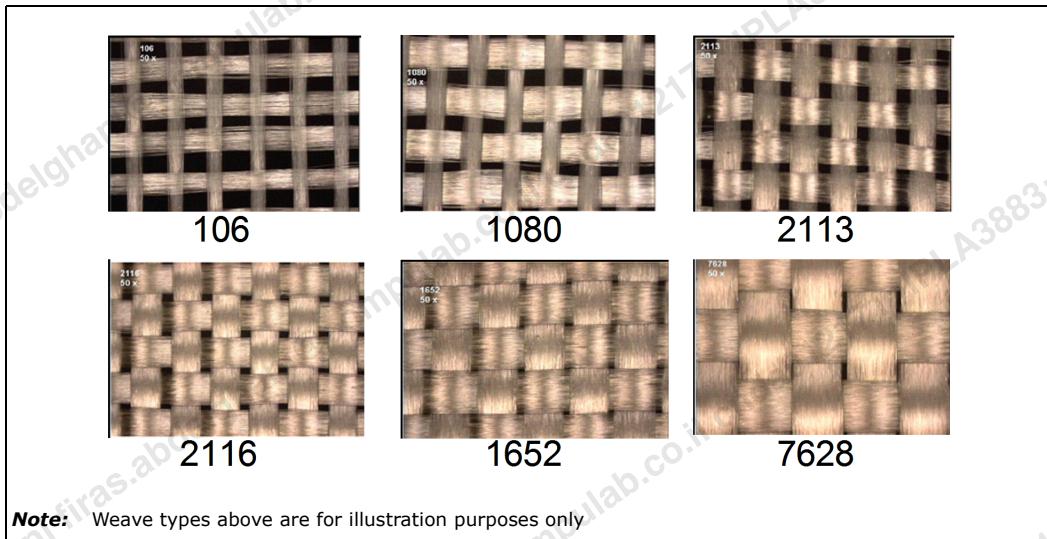
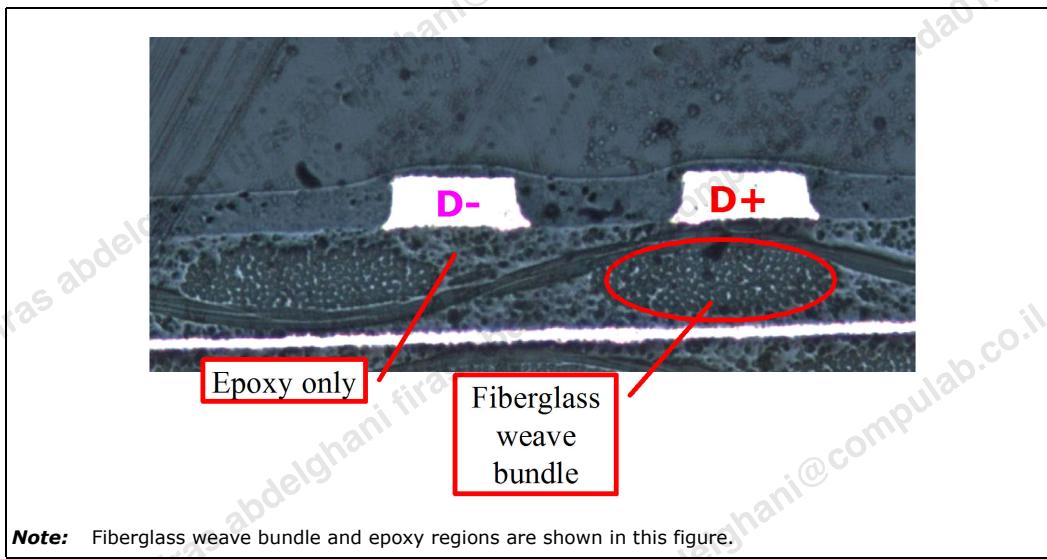
Figure 2-15. Single Ended Kb Diagram


Figure 2-16. Differential Kb Diagram

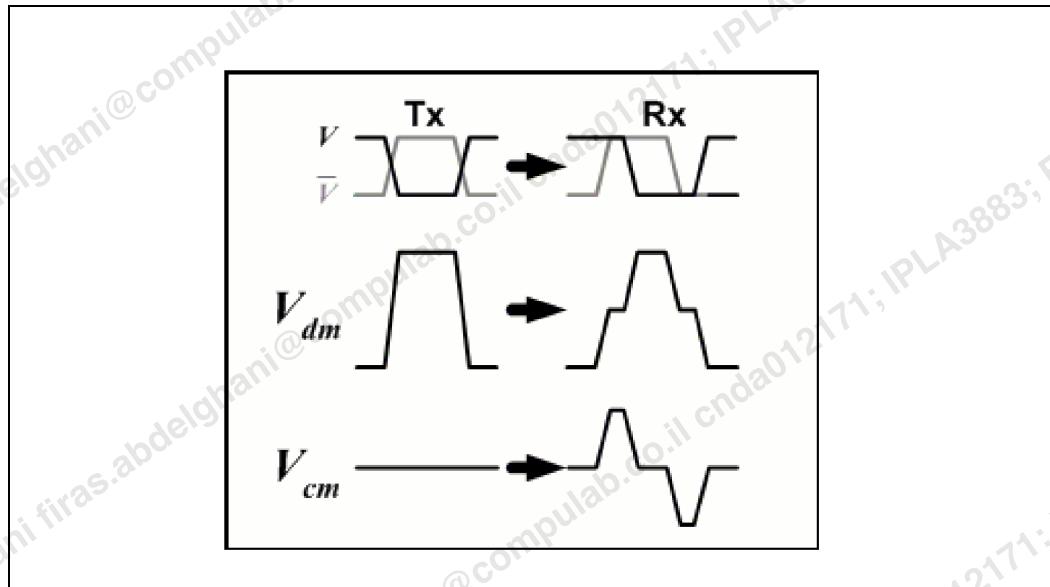
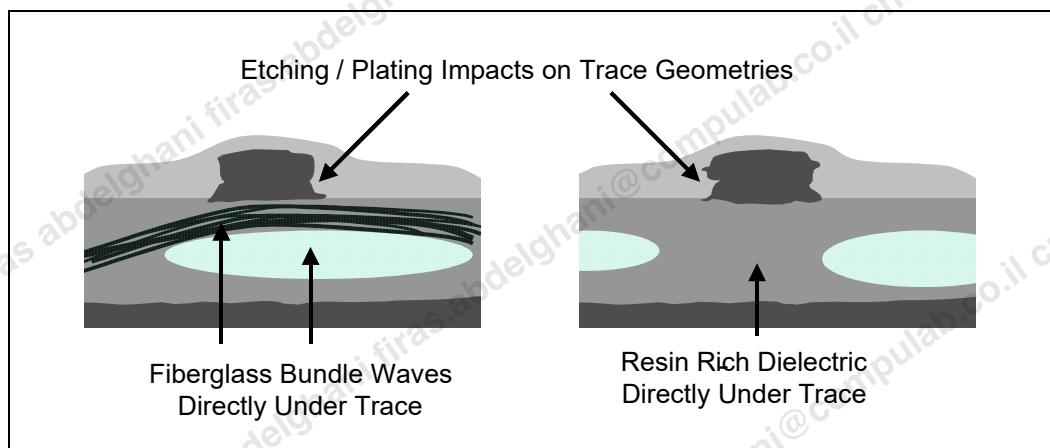
2.9 Minimizing the Effect of Fiber Weave

2.9.1 Overview of Fiber Weave

Fiber weave in the PCB material impacts the routing of high-speed traces. The PCB material is made up of a composite of fiber and resin. The strands of fiber run perpendicular to each other. Depending on the orientation of the weave relative to the trace, there could be either resin or a fiber bundle beneath the trace. Due to the differing dielectric constants of these two materials, a phase skew could be introduced among signals that comprise a differential pair. This phase skew manifests itself as an AC common mode noise at the receiver, affecting both voltage and timing margin at the receiver. The layout recommendations in this section will minimize the effect of the PCB fiber weave on the routing of differential signals. The choice of a particular mitigation technique is dependent on the configuration and layout of the platform and, hence, this choice is left to the platform designer. Typical printed circuit boards, due to their basic construction consisting of woven fiberglass fabric ($\epsilon_r \sim 6$) strengthened and bound together with epoxy resin ($\epsilon_r \sim 3.5$), present a non-homogeneous medium for signal propagation of differential pairs. As shown in [Figure 2-17](#), there are several weave types, with the weave strands running horizontal and vertical relative to the board edges. For differential pairs with trace width and spacing comparable to the dimensions of the fiberglass cloth, the PCB's non-uniform dielectric can give rise to substantial propagation differences between the conductors of the pair, refer [Figure 2-18](#).

Figure 2-17. Common Glass Cloths Used in PCB Manufacture**Figure 2-18. Inhomogeneous Nature of a PCB as Shown in this Cross-Section**

At high data rates this skew can amount to a substantial fraction of the transmission unit interval, resulting in an increased common mode voltage and a correspondingly degraded differential signal (Figure 2-19). In addition, the resulting common mode signal (ACCM) can become a source of increased crosstalk and EMI in the system, or violate receiver ACCM specifications.

Figure 2-19. Effect of Skew on Differential and Common Mode Signals**Figure 2-20. Cross-Section of PCB Indicating Effect of PCB Fiber Weave**

Fiber weave effect is noticeable for routing lengths greater than 2" and this effect gets more pronounced for longer trace lengths. There are many approaches to minimize this effect and the next three sections suggest some methods to mitigate this effect. The AC common mode noise causes considerable degradation of the signal for trace lengths in the range of 5" to 15" for a typical PCB stack-up on FR4 material.



2.9.2 Fiber Weave Effect versus Transfer Rate and Trace Length

Table 2-16. Max Root Square Sum (RSS) Length versus Transfer Speed

Transfer Speed	Max RSS length (See note 1)
2.5 GT/s	5"
4 GT/s	4"
5 GT/s	3"
6.4 GT/s	2.5"
8 GT/s	2"

Notes:

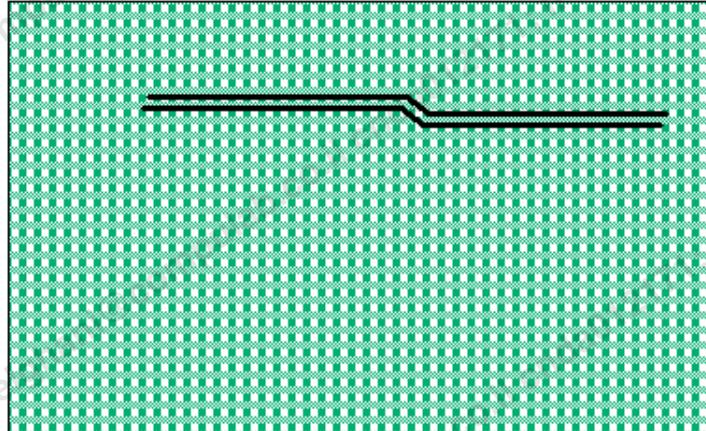
1. The lengths in the table represent total trace lengths that are aligned to the weave (that is, parallel to the manufacturing panel's edge). Actual routing may have a significant portion of the length at angles to the edge of the board- those lengths should not be considered in this analysis.
The total length is the Root Square Sum of total vertical and horizontal lengths that run parallel to the weave:
$$\text{Length} = (H_1)^2 + (H_2)^2 + (H_3)^2 + (V_1)^2 + (V_2)^2 + (V_3)^2 + \dots$$
where:
 - a. Hx = length of each segment routed horizontally, and
 - b. Vx = length of each segment routed vertically
2. The table represents an approximation only, based on simulations of "representative" topology. The exact fiber weave may vary, depending on the exact topology.

2.9.3 Specific Routing Configurations

Some platforms might have their components laid out in a manner that requires non-orthogonal (to the PCB board edge) routing for their high-speed busses. Orthogonal routing up to a maximum length of 2" does not result in a noticeable impact on the differential signals. However, there could be a significant amount of AC Common-Mode voltage introduced between the differential pair that the platform designer will need to consider.

2.9.4 Offset Routing

This involves routing the trace in a straight line with offset in the middle equal to a glass bundle pitch. The glass bundle pitch differs by materials and direction and is dependent on the particular manufacturing process. An example is shown in figure below. For this technique to be applied, a PCB layout tool with this capability would be required.

Figure 2-21. An Example of Offset Routing

2.9.5 Zig-Zag or Slanted Routing

If the weave is aligned to the PCB edges, follow a zig-zag or slanted routing of differential traces. Maintain a minimum angle of 10 degrees between the trace and fiber weave. This will lead to traces that are angled relative to the PCB edge.

Figure 2-22 is an example of zig-zag routing. Figure 2-23 shows slanted routing. For this technique to be applied, a PCB layout tool with this capability would be required.

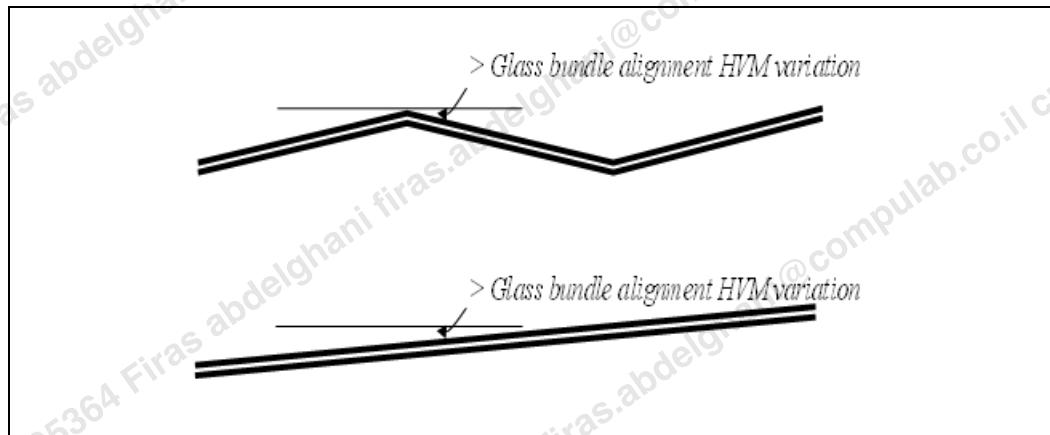
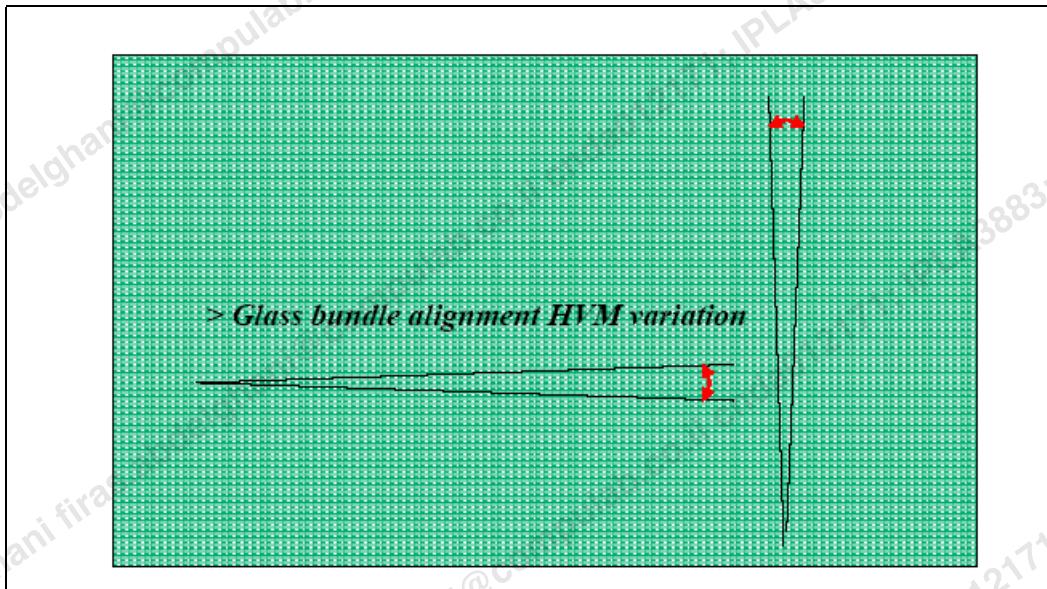
Figure 2-22. An Example of Zig-Zag Routing

Figure 2-23. An Example of Slanted Routing

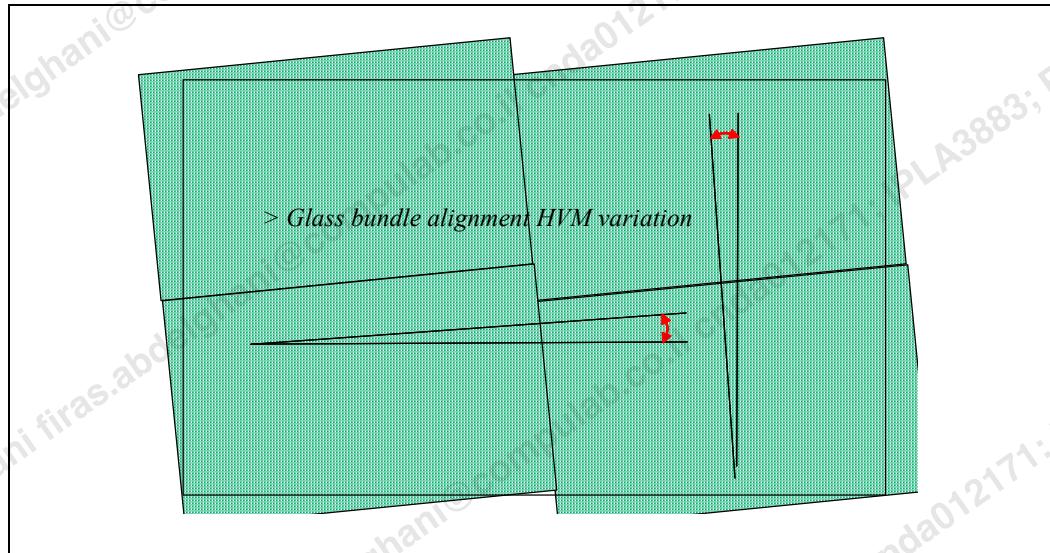
2.9.6 Image Rotation

Another solution is to maintain an angle between the trace and the fiber weave pattern is to rotate the weave relative to the edge of the PCB, thereby maintaining differential trace routes aligned with edges of the PCB (refer to [Figure 2-24](#)). It is recommended the rotation be such that the traces are at a 10 degree angle relative to the fiber weave. The rotation can be achieved by cutting the PCB board at an angle, as shown in [Figure 2-24](#), or by rotating the layout database relative to the edge of the PCB board. The latter requires the use of an appropriate PCB routing software that has this capability.



2.9.7 Using Alternate PCB Materials

Figure 2-24. An Example of a PCB Cut Such That Its Edges are Rotated Relative to the Fiber Weave Pattern



The fiber weave effect can also be minimized by using PCB material that exhibits less variation in the dielectric coefficient E_r between the epoxy and glass materials.

2.10 Flexible Printed Circuit Consideration

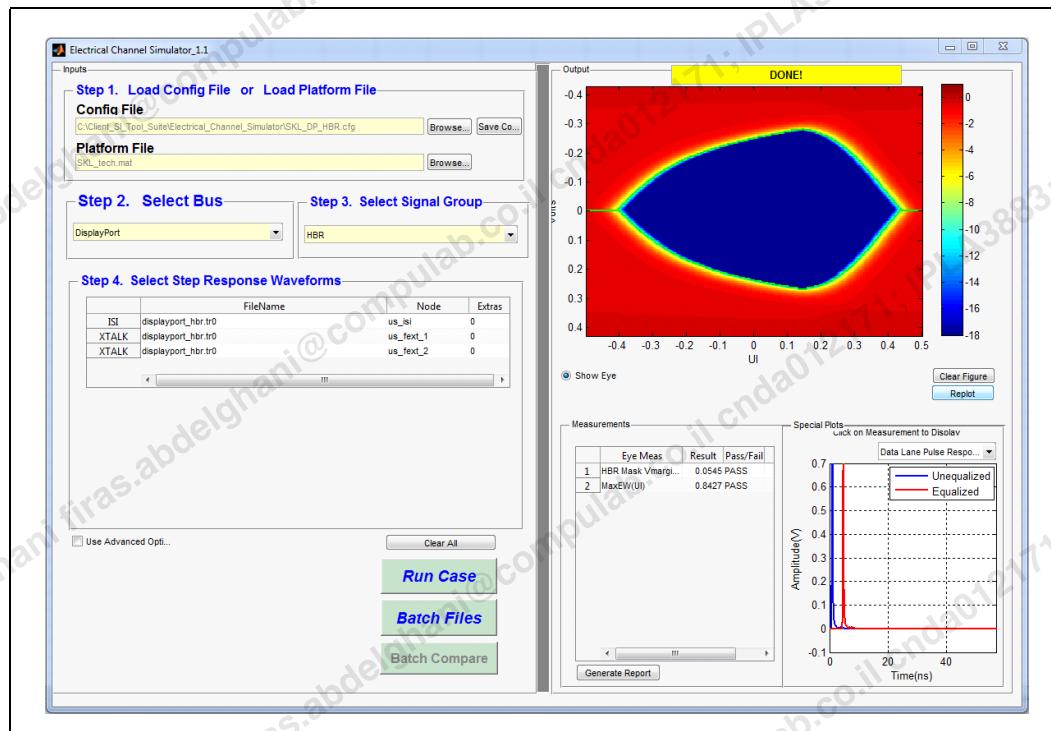
Internal cables are widely used inside computing devices, ranging from phone, camera, tablet, and notebook. They are usually non-standard or customized and may include regular cables such as discrete wires, twisted pairs, twin-axial and coaxial wires, as well as FFC (Flexible Flat Cable) and FPC (Flexible Printed Circuit).

With the usages becoming more common, designers are gaining awareness on the importance of cable selection. Flexibility, impedance, crosstalk, EMI and RFI, have always been the factors in cable selection. Refer to RDC#550502 on "Flexible Printed Circuit Electrical Characterization and Recommendation"

2.11 Coffee Lake Client Signal Integrity Tool Suite

Coffee Lake Client Signal Integrity Tool Suite RDC#572252 is pre-silicon signal integrity tools targeted for Coffee Lake based design. The tool Suites includes Electrical Channel Simulator (ECS), TlineCalc, and freqMasterEx.

ECS provides customers with an advanced post processing simulation tool to assess the risk level and evaluate voltage and timing margins for any design that falls inside and outside of the PDG, as well as white papers. FreqMasterEX is a toolbox, mainly used to perform evaluation of S-parameter and create equivalent models to be used in ECS. Tline calc, as snapshot in Figure 2-30, is a tool in assisting customer in PCB board stack-up electrical characteristics calculation, to ease customer to compare these electrical characteristics to Intel's assumptions listed in the PDG.

Figure 2-25. Snapshot of Electrical Channel Simulator (ECS)


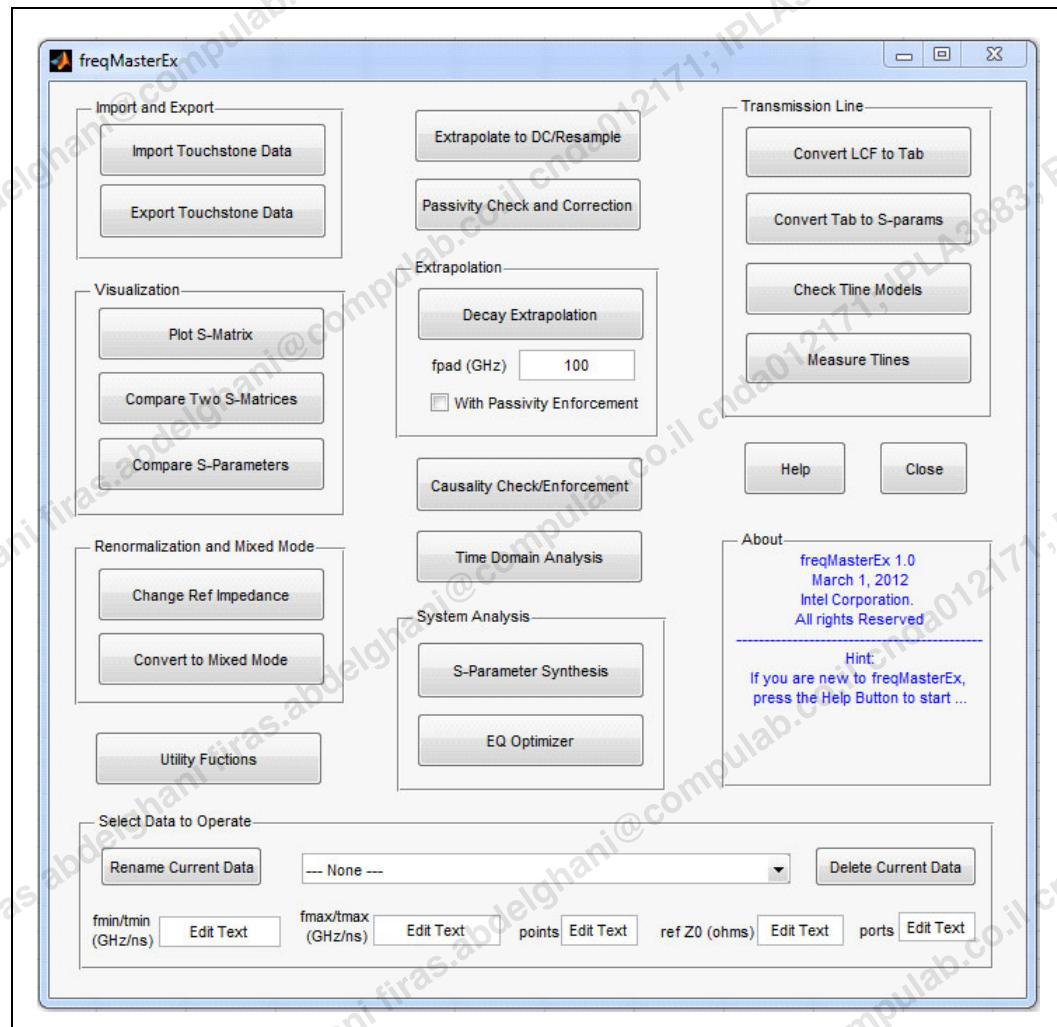
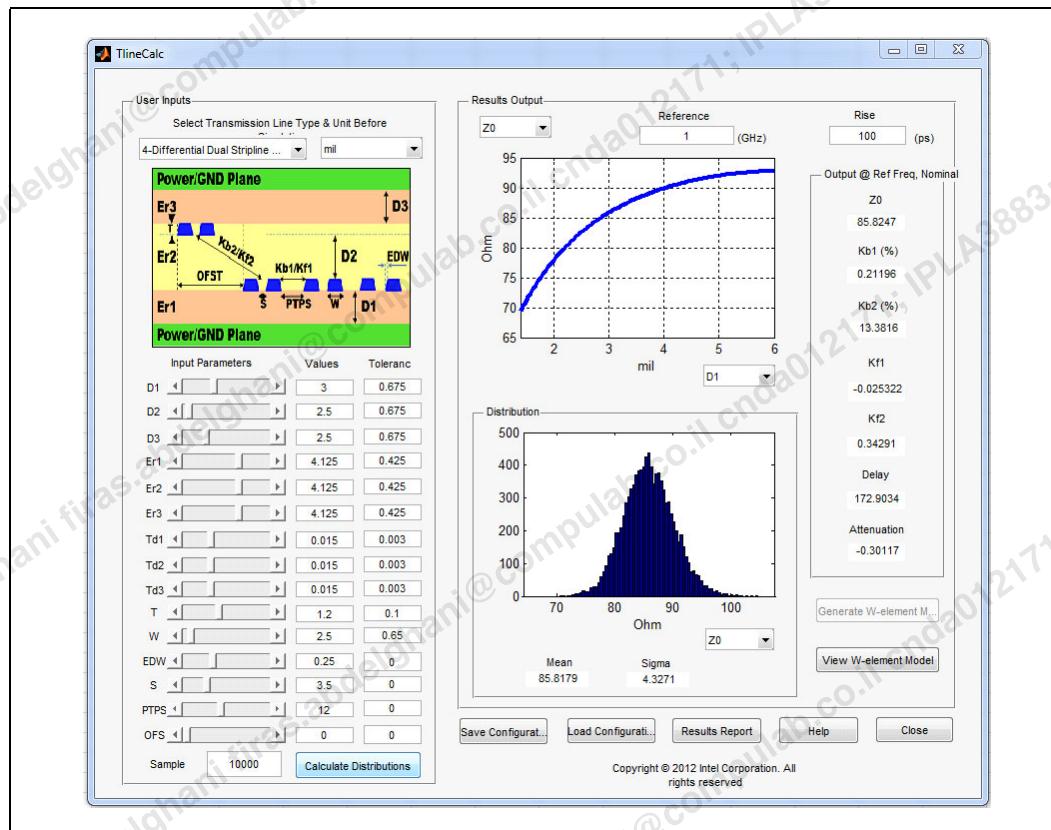
**Figure 2-26. Snapshot of freqMasterEx Toolbox**



Figure 2-27. Snapshot of TlineCalc



§ §



3 General Differential Design Guidelines

3.1 General Differential Stackup Guidelines

3.1.1 Stackup and Layer Utilization Guidelines

3.1.1.1 General Dual-Stripline Support

In cases where high speed differential signals (PEG, DMI, or eDP, etc) are routed in an 8- or 10- layers dual-stripline stack-up, follow the guidelines in [Table 3-1](#). [Figure 3-1](#) illustrates the meaning of Tx-over-Tx, Rx-over-Rx, and Tx-over-Rx.

Table 3-1. General Dual-Stripline Support

Tx -over-Rx Parallel Routing	Tx-over-Tx or Rx-over-Rx Parallel Routing	Tx-over-Rx or Tx-over-Tx or Rx-over-Rx Routing Orthogonal or with Angle
<ul style="list-style-type: none"> Parallel routing not allowed Route with an offset of 15mil or greater as shown in Figure 3-3. 	<ul style="list-style-type: none"> A maximum of 2 inches of parallel routing is allowed 	<ul style="list-style-type: none"> Routing at an angle of at least 30 degrees significantly reduces layer-to-layer crosstalk. Route differential pairs at a 30, 45, 60, 90 etc degree angle. Figure 3-2 shows orthogonal routing. Figure 3-4 shows angled routing at less than 90 degrees. Allow maximum of 10 aggressor pairs to route over 1 DSL routing victim pair.

Figure 3-1. Tx-over-Tx, Rx-over-Rx, and Tx-over-Rx

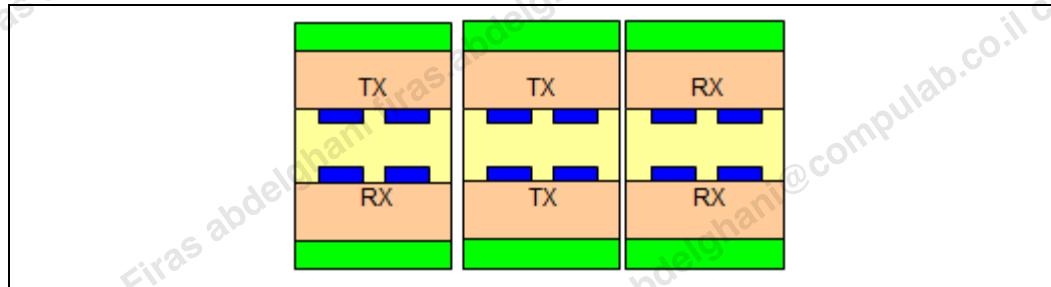


Figure 3-2. Dual-Stripline Orthogonal Routing Recommendation

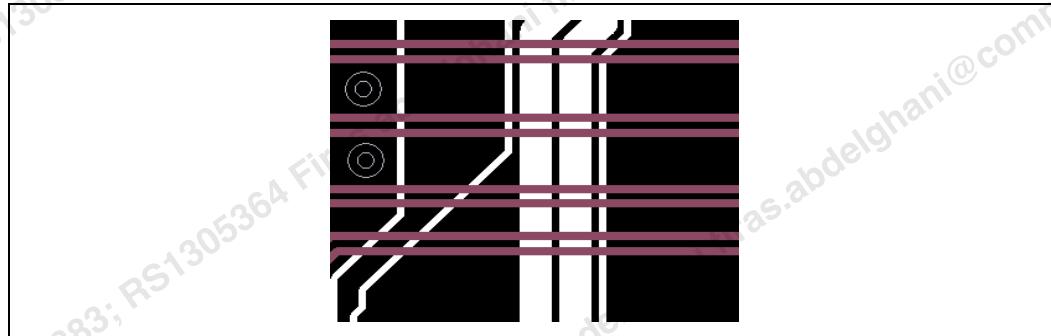


Figure 3-3. Dual-Stripline High Speed Signal Dual Layer Routing Recommendation

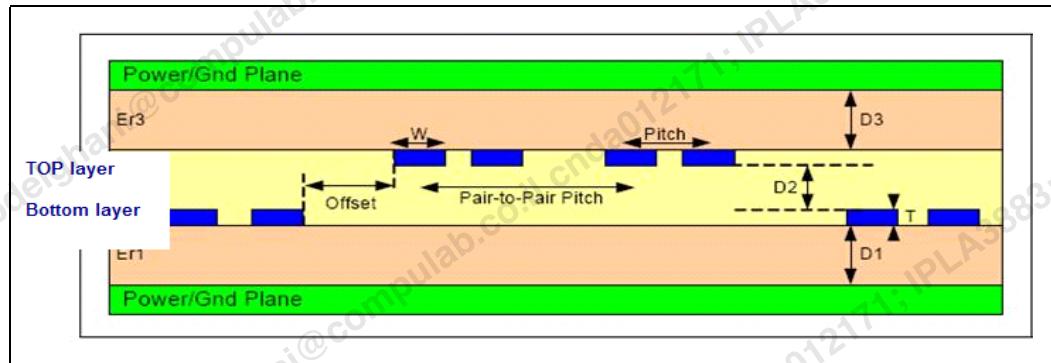
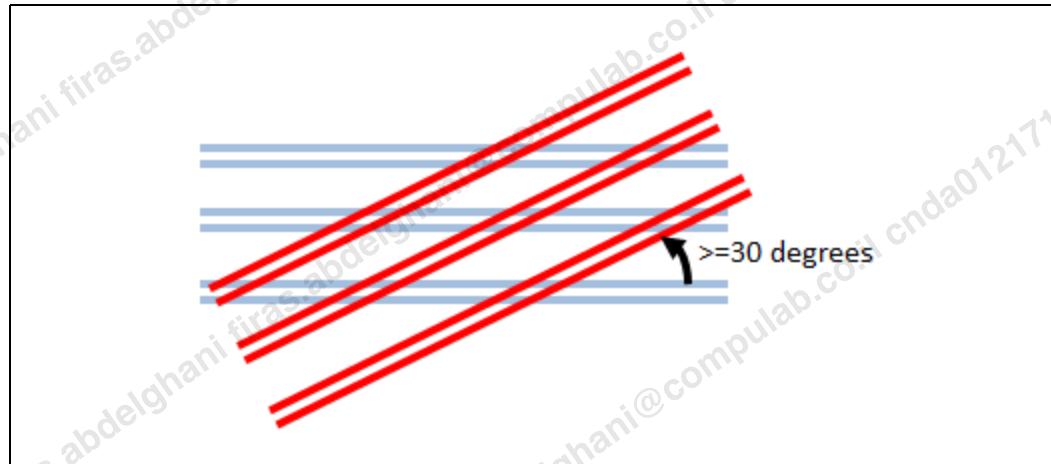


Figure 3-4. Recommended Routing Angle to Reduce Layer-to-Layer Crosstalk





3.2 General Differential Routing Guidelines

3.2.1 Breakout Example and Guidelines

Maintain differential routing rules in package breakout areas.

Figure 3-5. Board Breakout Example

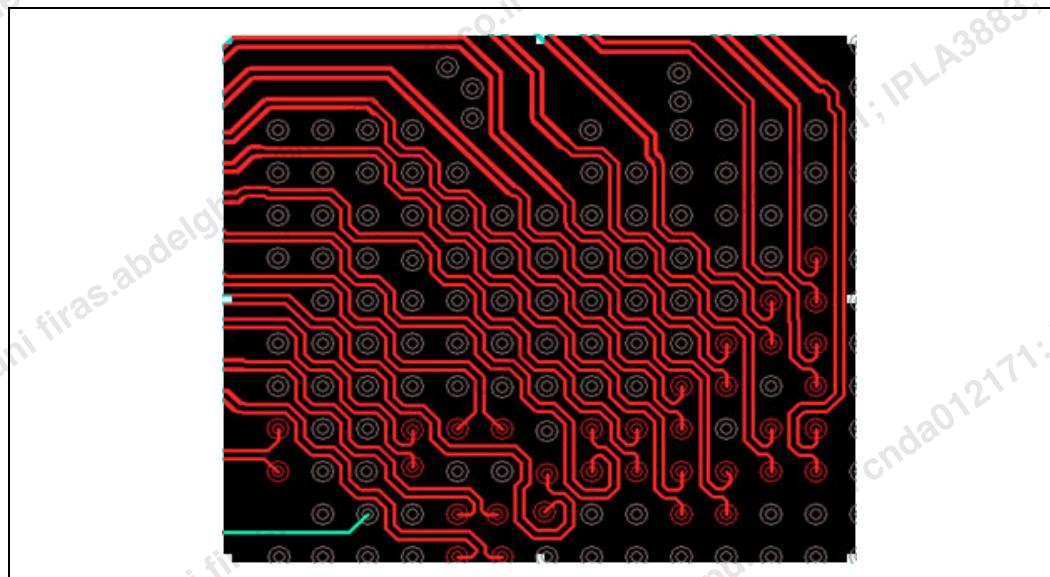
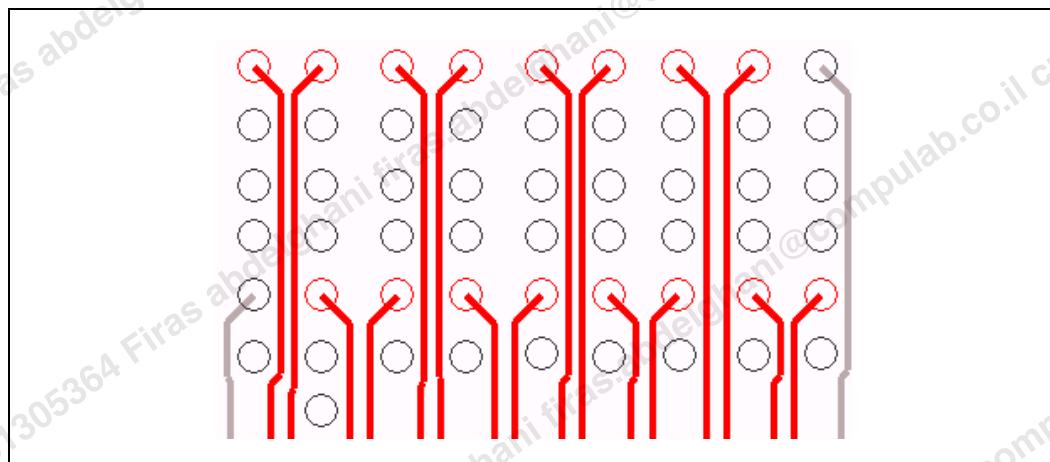


Figure 3-6. Board Breakout Example



Guidelines are as follows:

- **Differential-pair pitch** is measured from the center of each trace in the differential-pair. The distance from the center of either trace in a differential-pair to the same point of reference on an adjacent differential-pair is described as **interpair pitch (IPP)**. Refer [Figure 3-7](#) for the illustration of differential-pair pitch and IPP.

- **Differential-pair space** is measured from the edge of each trace in the differential-pair. The distance from the edge of one trace in a differential-pair to the near edge of an adjacent differential-pair is described as pair-to-pair space. Refer [Figure 3-7](#) for the illustration of differential-pair space and pair-to-pair space.
- Maintain the best possible **lateral routing symmetry** between the two signals of a differential-pair. (refer [Figure 3-8](#)).
- Breakout routing geometries can be found in the PCB Considerations section.

Caution:

Maintain routing symmetry between the two signals of a differential-pair. Failure to maintain symmetry introduces an AC common mode voltage.

Caution:

Reduced trace width will increase losses due to skin effects and reduced spacing will increase crosstalk. Therefore, it is recommended to keep breakout routing as short as possible.

Figure 3-7. Differential-Pair Spacing Diagram

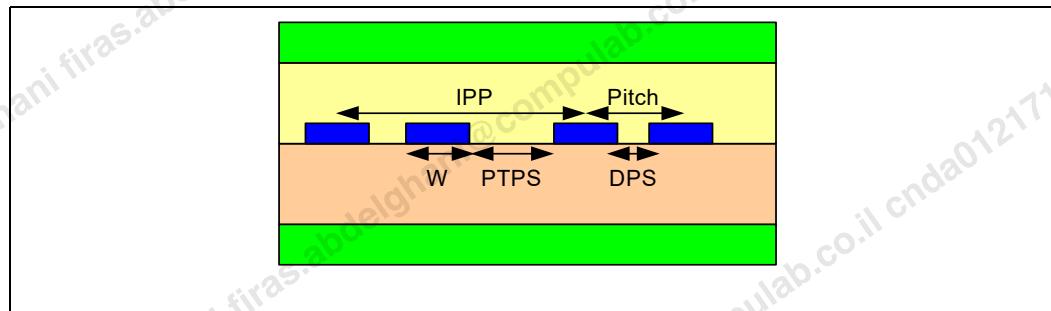
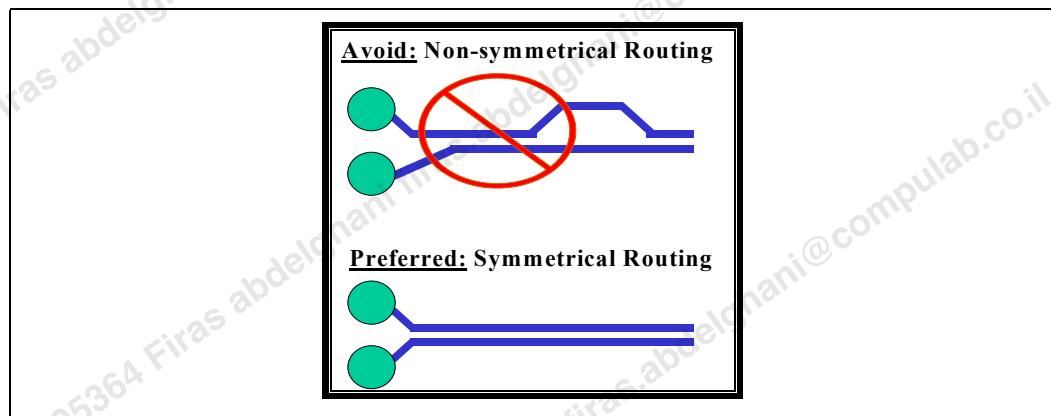


Figure 3-8. Symmetrical and Non-Symmetrical Routing Example



3.2.2 Differential I/O Routing Scheme Guidelines

Simulation results show that the receiving margin is severely degraded by near-end crosstalk (NEXT) from adjacent Transmit signals. Thus, non-interleaved breakout is required to mitigate concerns on near-end crosstalk.

The Cannon Lake PCH-H package ballmap has most of Tx signals on outer balls and Rx signals on inner balls to help facilitate non-interleaved breakout.

The recommended implementation is illustrated in [Figure 3-9](#), HSIO Tx and HSIO Rx signals are breakout on different board layers or have TX and RX lane at least 15 mils spacing separations.

Figure 3-9. HSIO Non-interleaved Breakout Guidelines

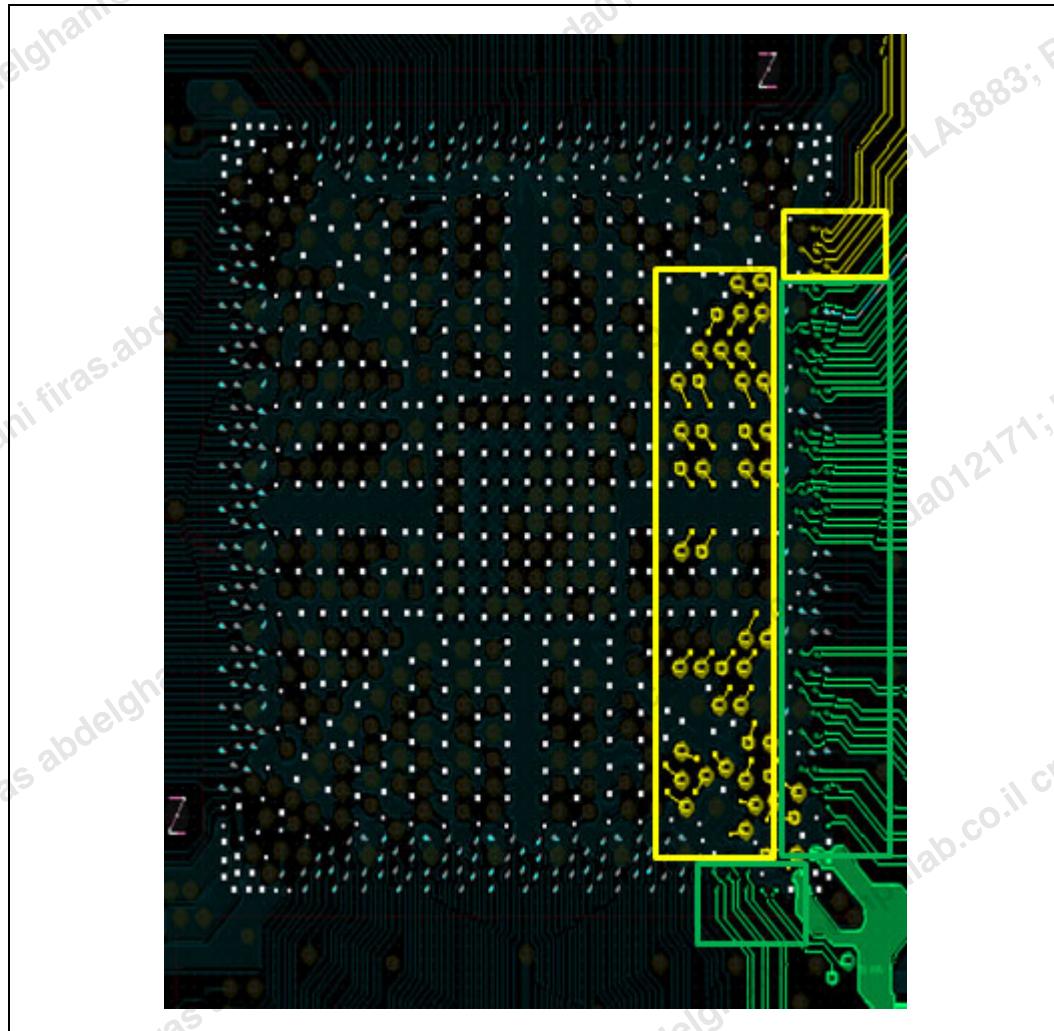
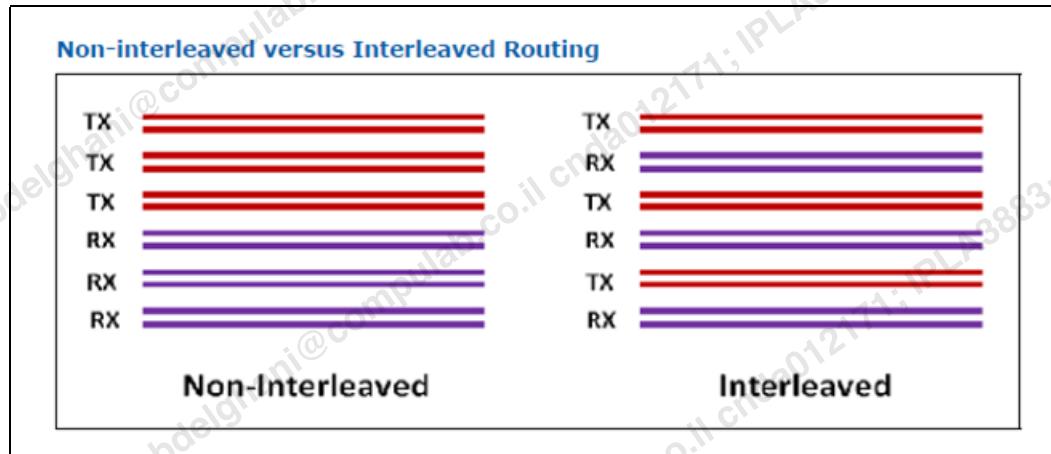


Figure 3-10. Non-interleaved versus Interleaved Routing

In further suppressing the far-end crosstalk (FEXT), interleaved or semi-interleaved routing is recommended in main routing region.

As illustrated in [Figure 3-11](#), routing scheme changed from non-interleaved in breakout region into interleaved or semi-interleaved in main routing region.



Figure 3-11. HSIO Interleaved or Semi-Interleaved Main Routing

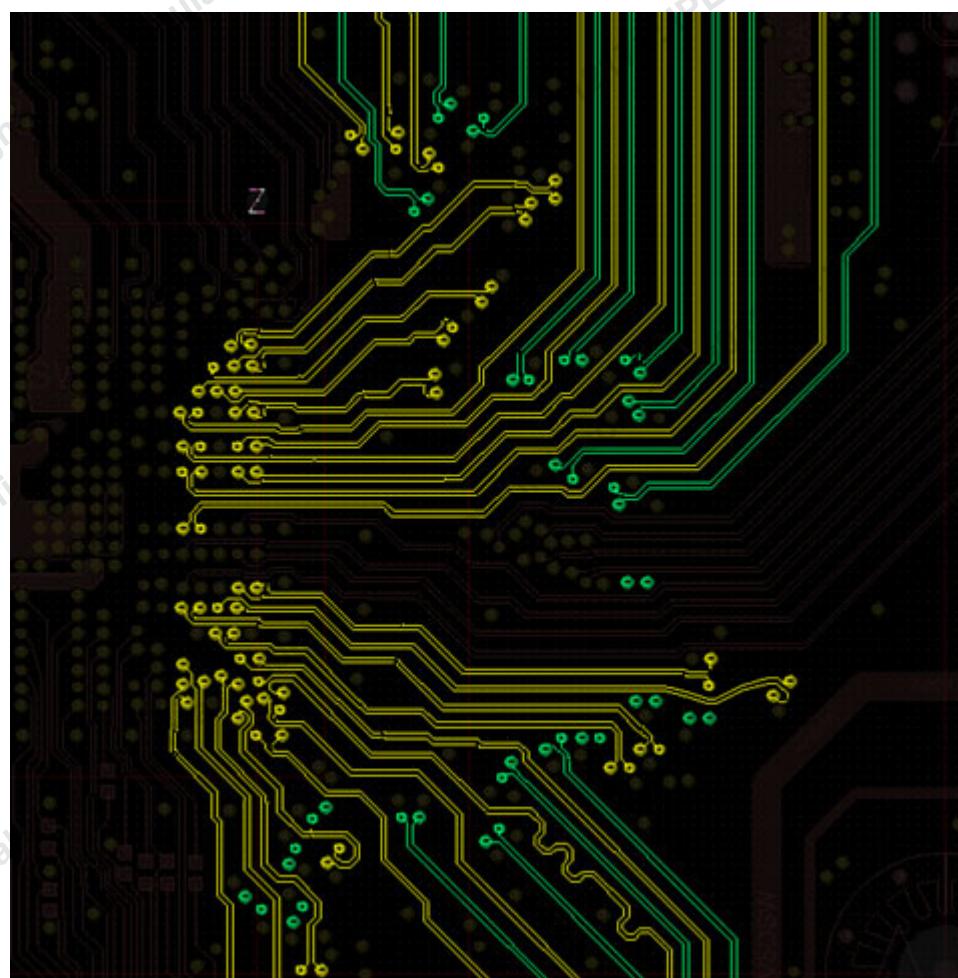
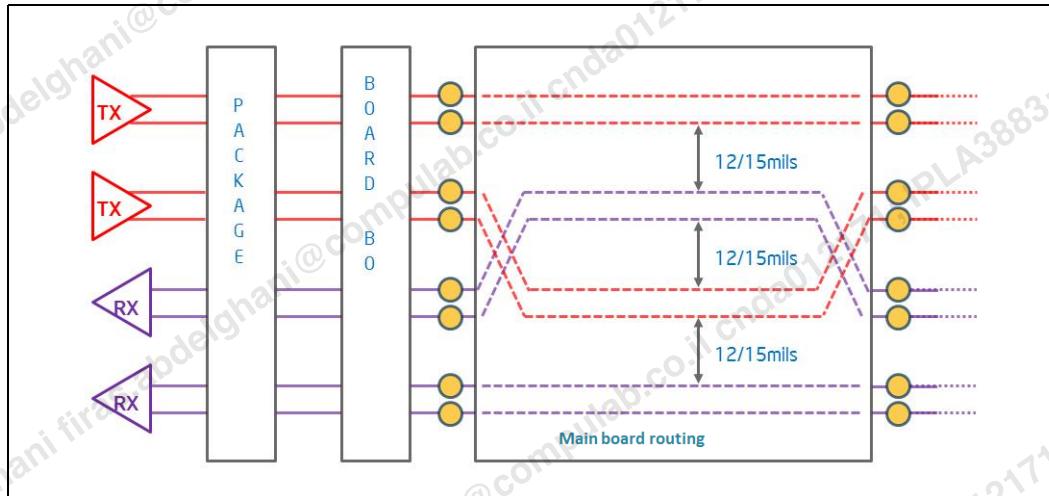


Figure 3-12 illustrates the full board routing recommendation, from package ball to device.

Figure 3-12. Differential Routing Guidelines



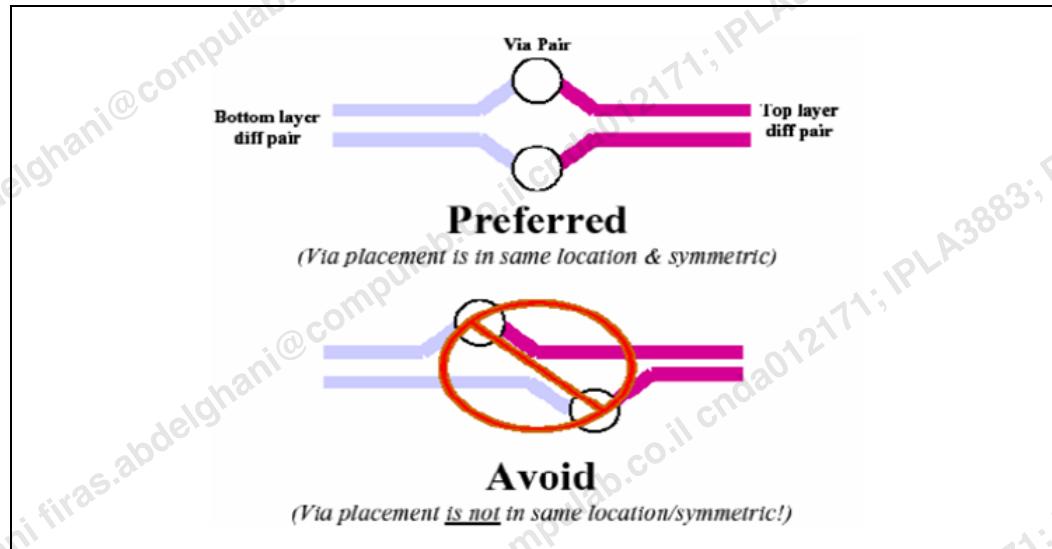
3.3

General Differential Optimization Guidelines

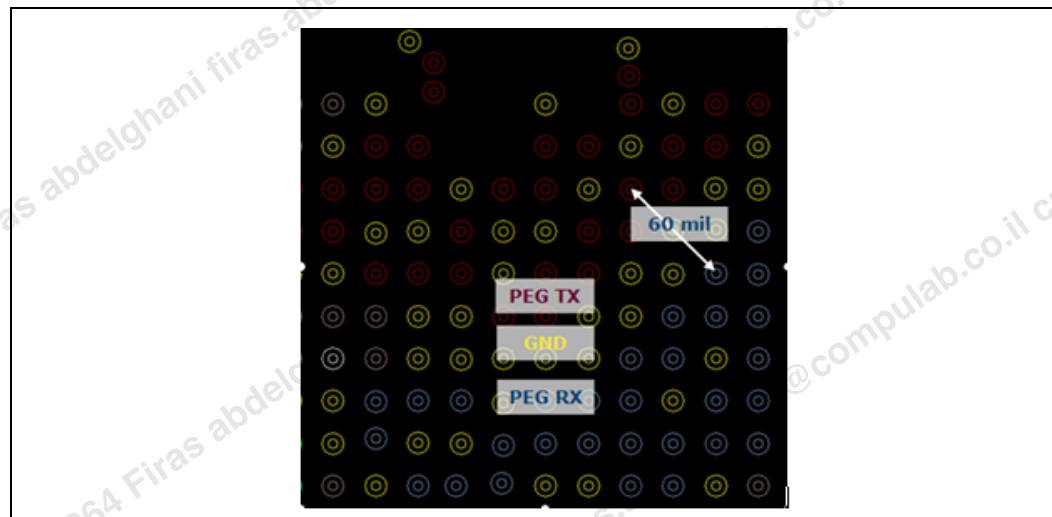
3.3.1

Via Placement and Via Usage Optimization

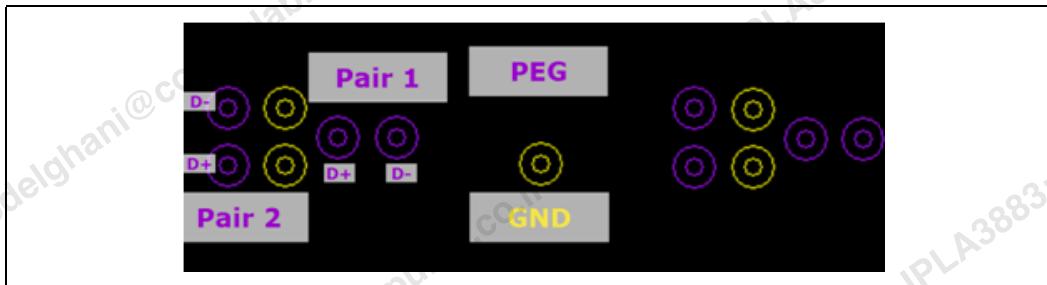
- Vias impact the overall loss and jitter budget. Routing signals with a minimal number of vias.
- The via count can be reduced but not increased from the maximum interface via requirement.
- Long via stub degrades overall signal integrity margin. Specific via stub length requirements may be defined within the interface design guideline chapters. For MS to SL/DSL routing recommendation on CFL H platform, routing recommendation has covered via stub length as below.
 - PEG <=10 mils
 - DMI /DP/PCH IO <=25 mils
- Remove pads from unused internal layers to minimize excess via capacitance.
- The differential-pair via placement must be symmetrical. Vias on the differential-pair should not only match in number but also in relative location.

**Figure 3-13. Via Pair Example**

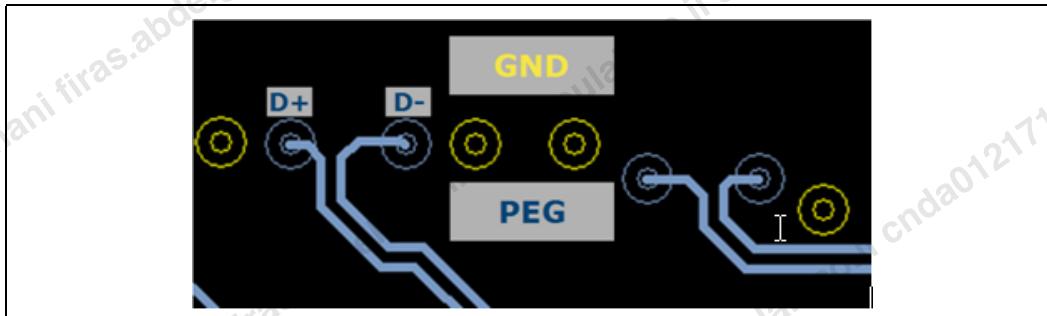
Note: The via placement examples below apply to all high speed interfaces such as PEG, DMI, eDP, and PCH PCIe3.

Figure 3-14. Example - Via Placement 1

- The symmetric via pattern in Figure 3-15 below minimizes crosstalk between 2 differential pair, therefore the recommendation is to implement the pattern according to area availability.

Figure 3-15. Example - Via Placement 2

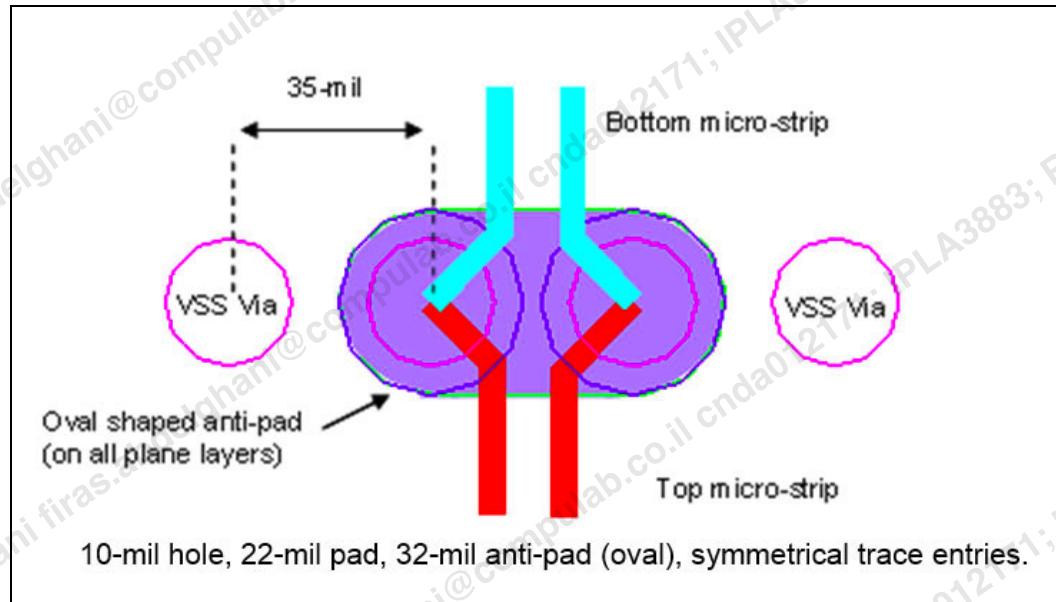
- For differential interfaces it is recommended 1:1 ratio of signal to GND via everywhere it is possible ([Figure 3-16](#)).

Figure 3-16. Board Breakout Example - Via Placement 3

3.3.1.1 Differential Transitional Via Recommendations

Transitional vias will use oval-shapes anti-pads on all plane layers. This can be created using a rectangular-shaped void to overlap with the usual round-shaped via anti-pad. The vias must also have a symmetrical trace entry.

[Figure 3-17](#) and [Table 3-2](#) provides the transitional differential via pad stack details.

Figure 3-17. Differential Transitional Via Layout**Table 3-2. Differential Transitional Via Layout Recommendations**

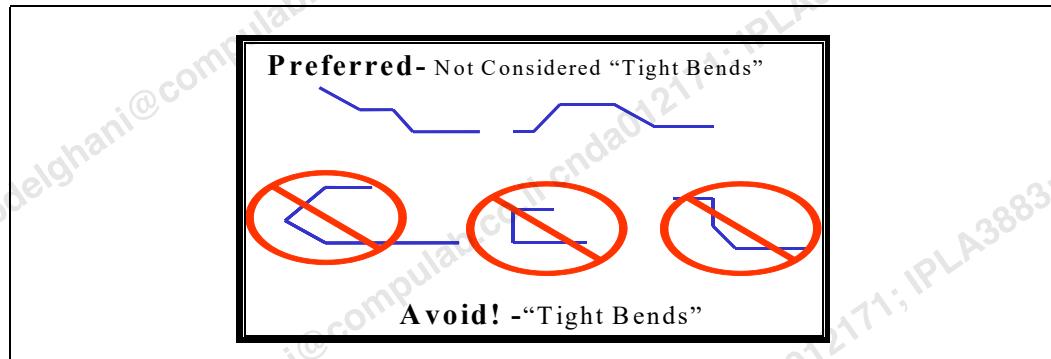
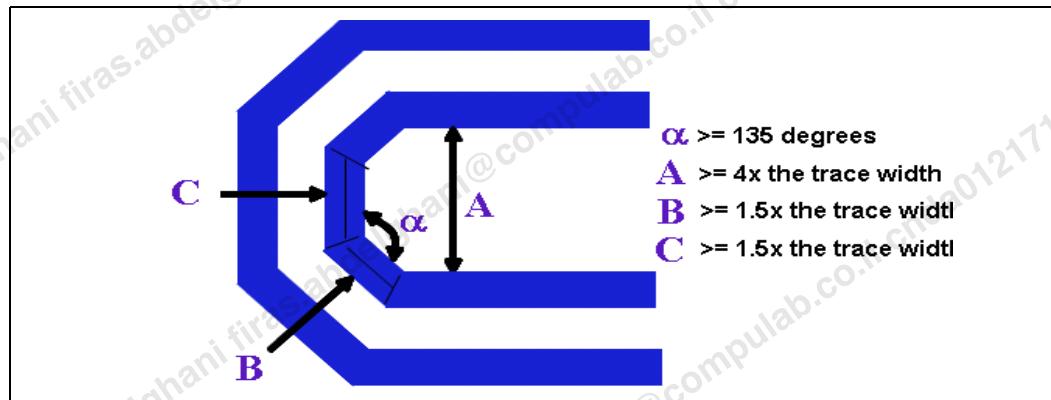
Parameter	Units	Recommendation
Via Diameter	mils	10
Via Pad Size	mils	22
Oval-Shaped Anti-Pad Size	mils	32
Via-to-via Distance (centered)	mils	35

3.3.2 Bend Optimization Guidelines

Bends are a necessary component in routing differential signals. Guidelines for bends are as follows:

- Keep bends to a minimum. Bends can introduce common mode noise into the system, which can affect the signal integrity of the differential signal pair.
- If bends are required, they should be at a 135-degree angle or greater; there should be no 90-degree bends or turns. An adequate air gap should be maintained between the inside traces of a bend. The gap should be 4 times the trace width or greater. The lengths of the segments in a bend should be 1.5 times the trace width or greater. Refer [Figure 3-18](#) and [Figure 3-19](#) for examples.
- Match the number of left bends to the number of right bends to minimize skew due to length differences between each signal of the differential-pair.
- Alternate between left and right bends.

Matching the number of right and left turns and alternating bends helps to minimize the amount of skew between rising or falling edges, which minimizes the differential to common mode conversion.

Figure 3-18. Acceptable Bends vs. Tight Bends Example

Figure 3-19. Maximum Bend Angle


3.3.3 Component Footprint Optimization Guidelines

Voiding the Ground/Power plane on the layer directly underneath SMT signal pads can help to minimize impedance mismatch caused by the SMT pads. This is recommended for large SMT pads of components such as ESD protection devices, Common Mode Chokes (CMC) and connectors. In general, the reference plane should be voided with the same size as the SMT pad. Voiding is only required on the layer directly underneath SMT signal pads and not required on any other internal layers. Voiding is not required for small components pads such as 0402 components and AC capacitors.

3.3.4 General Routing Guidelines

- DO NOT route traces under power connectors, power delivery inductors, other interface connectors, crystals, oscillators, clock synthesizers, magnetic devices or ICs that use and/or duplicate clocks. DO NOT place stubs, test points, test vias on the route to minimize reflection. Utilize vias and connector pads as test points instead. If a stub is unavoidable in the design, the total of all the stubs on a particular line should not be greater than 200 mils.
- It can be helpful for testability to route the TX and RX pairs for a given port on the same layer and close to each other to help ensure that the pairs share similar signaling characteristics. If the groups of traces are similar, a measure of RX pair layout quality can be approximated by using the results from actively testing the TX pair's signal quality.



- Separate signal traces into similar categories, and route similar signal traces together (such as routing differential pairs together).
- Keep signals clear of the core logic set. High current transients are produced during internal state transitions and can be very difficult to filter out.

3.4

General Differential Length Matching Guidelines

3.4.1

Length Matching and Length Formulas

Follow the specific interface length matching guidelines if provided. If not provided, use the below as a general guideline. This guidelines is to minimize signal integrity, EMI and RFI problems.

Table 3-3. General Differential Pair Length Matching

Description	Units	Routing Recommendation
Within Layer Max Mismatch	mils	+/- 10
Total Length Max Mismatch	mils	+/- 5

Note:

1. Preferred to keep both "within layer max mismatch" and "total length max mismatch" within 5 mils

The following are the length matching guidelines for differential-pairs:

- Each signal and its complement in a differential-pair should be length matched whenever possible on a layer-by-layer basis at the point of discontinuity. 'Within-layer' matching means that differential pairs should be matched within 10 mils before transitioning to a different layer. At any via transition the n/p mismatch for the entire route preceding the via cannot exceed 10 mils.
- When trace length matching, the matching should be made as close as possible to the point where the length variation occurs, as shown in [Figure 3-20](#), so the discontinuity won't propagate across the channel. For example, length matching in a chipset breakout area or connector pin field should occur within first 125 mils (3.175 mm) of the structure that causes mismatch.
- Serpentine layout introduces discontinuity to the channel and should be minimized so as to make it transparent to the signal. This is done by making its electrical length shorter than the signal rise time. In general, keeping serpentine routing length <100 mils is adequate. Trace spacing should not become greater than two times the original spacing. Refer [Figure 3-21](#).
- In determining the overall length of a given signal in a differential-pair, use pad or pin edge-to-edge distances rather than the total etch present, unless the amount of trace routing inside each pad is identical. The amount of etch within a given pad is electrically part of the pad itself. In other words, only the etch outside of the pad edge is relevant to the overall length of a differential-pair. For example:
 - If the P signal of the differential-pair has an extra 5 mils (0.127 mm) of etch length compared to the N signal, and the extra 5 mils (0.127 mm) occurs due to extra etch extending into a component pad, the two signals should be considered identical length.

- Similarly, trying to length match signals by adding etch inside a pad boundary (such as extra bends inside the pad itself) does not produce the intended length matching effect on the interconnection (refer Figure 3-22).

Figure 3-20. Example - Length Matching

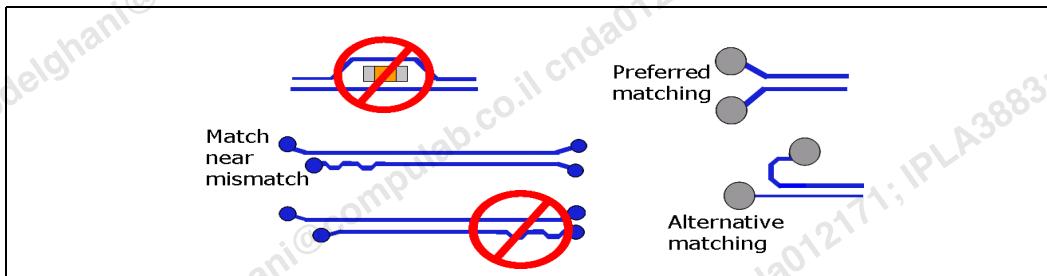


Figure 3-21. Example - Serpantining

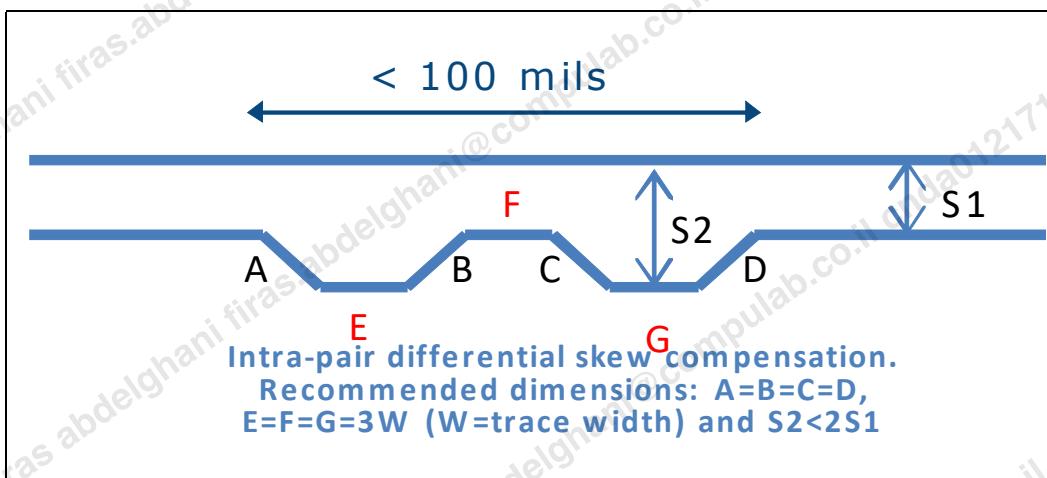


Figure 3-22. Example - Etch Located within a Pad

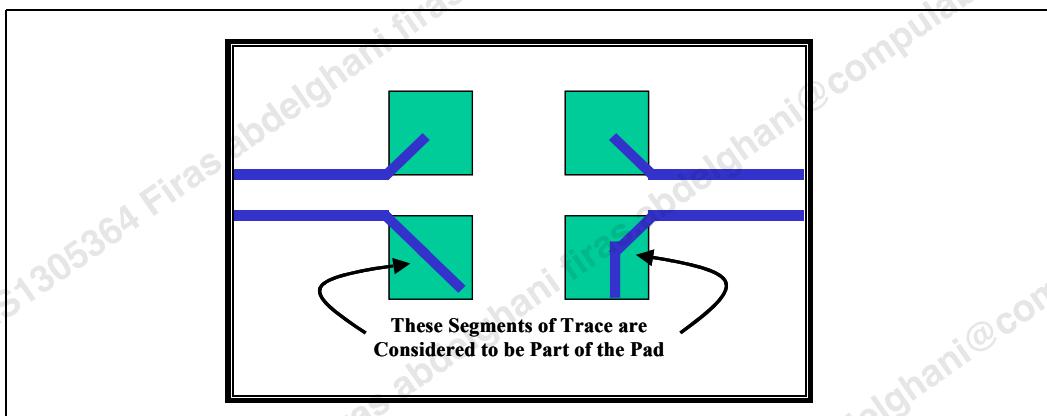
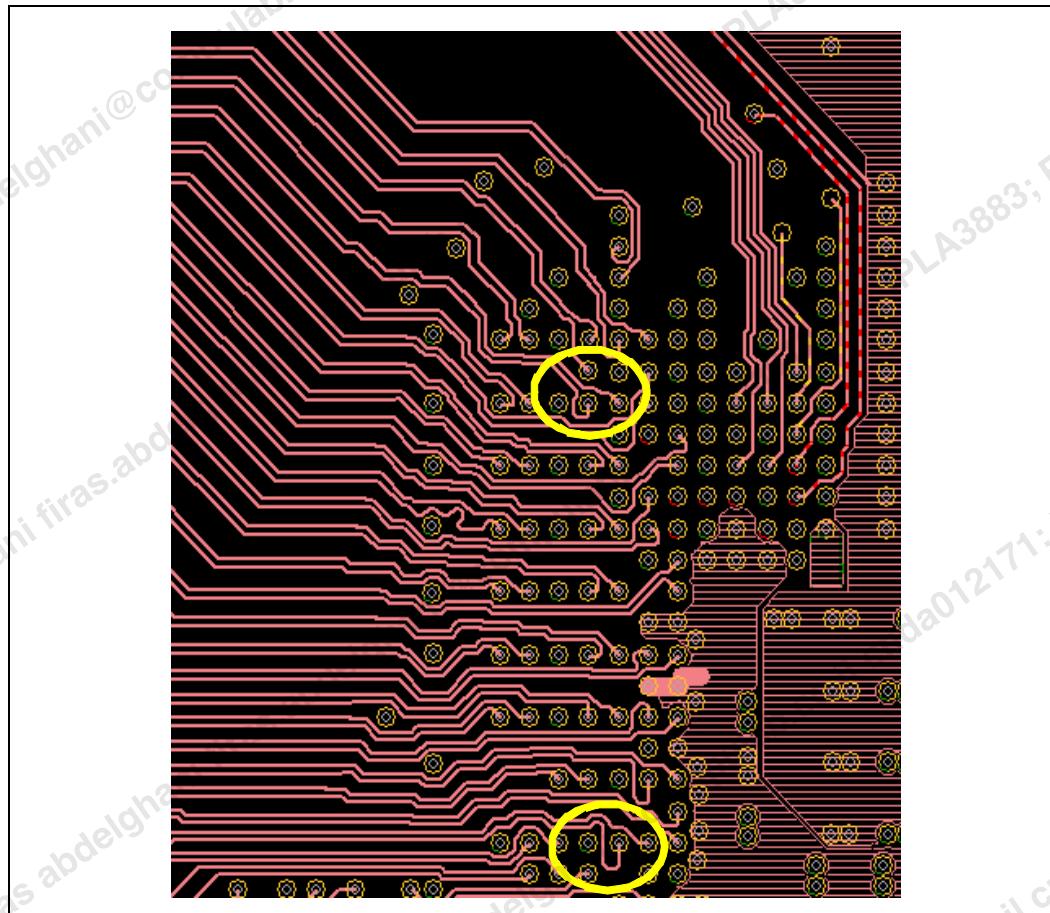


Figure 3-23. Example - Good Length Matching**Figure 3-24. Example - Poor Length Matching**



3.5

General Differential Compensation and Voltage Reference Guidelines

3.5.1

RCOMP Signal Guidelines

Cannon Lake PCH-H uses a global Resistance compensation. The calculated values are used across all lanes for adjustment for termination values. Voltage across RCOMP and RCOMNN is measured differentially and hence matching is very critical. The RCOMP signals should be referenced to Vss and noisy or switching references should be avoided. As board space allows, recommend to add a VSS shield at least 4 mils wide placed between RCOMP and adjacent IO. It is important that these signals maintain low DC resistance routing ($<0.1 \Omega$), so they should be routed with wide and short traces. For the breakout from the PCH, a minimum trace width of 4 mils is allowed with a maximum of 100 mils. All other RCOMP and IREF should be routed with a minimum or 4 mils.

Avoid routing these signals next to clock pins or noisy signals, but a partial VSS shield (defined as a 4 mil VSS shield routed in between the IREF/COMP signals and any adjacent high speed IO) is recommended for RCOMP and IREF. There is no shielding required between RCOMP and IREF. In order to meet these requirements a minimum spacing of 12 mils is required between the IREF/COMP signals to any adjacent high speed IO.

3.5.2

Reference Planes

Guidelines for reference planes are as follows:

Note:

Reference all signal routing layers to a solid ground plane that is continuous over the length of the interconnect. This is an important requirement especially on high speed differential signal e.g. DMI, PEG, DDI, PCIe3, etc. Specific requirements may be defined within the interface design guideline chapters.

Note:

Using a power layer as a reference plane is allowed if the power layer is low noise and there is proper decoupling stitching at reference planes transitions to ensure high frequency return path continuity. However, this is only be allowed as the secondary reference plane on internal layers where a solid continuous ground reference is already present. Even in this case the power plane must be low noise due to the possibility of noise being coupled into the associated signal planes (referencing to noisy power planes that are used by switching VRs are not allowed).

Note:

Route noisy power planes on the same layers as signals to minimize fringe coupling by proper spacing separation.

Note:

Even when routed as coupled differential-pairs, one trace can experience more coupling to its reference plane than to its routing pair.

- Traces should avoid discontinuities in the reference plane, such as splits and other voids.
 - A good plane reference helps to minimize any AC common mode voltage found on the differential-pair as well as benefiting signal quality and minimizing EMI.
- When routing near the edge of their reference plane, traces should maintain at least a 40-mil (1.016-mm) space keepout from the edge of the plane.

**Note:**

Referencing signals going over a board-to-board connector must be considered and stitching capacitors should be added at the connector as appropriate. For example, if a differential-pair is GND-referenced on the motherboard and the pair is V_{CC} referenced on the daughter card, then stitching capacitors must be added at the connector between V_{CC} and GND.

- One reference plane should be used for the entire length of the trace route.
 - In a traditional 8-layer stack-up, there are two microstrip/stripline routing channel pairs that each share a common reference layer. It is preferred that any layer transitions switch between these two layers, within this layer pair. For example, Layer 1 and Layer 3 are tightly coupled to Layer 2 and form one layer pair; Layer 8 and Layer 6 are tightly coupled to Layer 7 and from another layer pair.
 - In a traditional 6-layer stack-up, there are two microstrip/stripline routing channel pairs that each share a common reference layer. It is preferred that any layer transitions switch between these two layers, within this layer pair. For example, Layer 1 and Layer 3 are tightly coupled to Layer 2 and form one layer pair; Layer 4 and Layer 6 are tightly coupled to Layer 5 and from another layer pair.
 - If this cannot be accomplished, stitching vias must be used to tie the two planes together. The vias should be located within 200 mils (5.08 mm) and in symmetry with the two signal vias to minimize return path discontinuities.
- Differential signals should not cross any plane splits or voids. However, it may be necessary for a trace to be partially routed over a via anti-pad void in the chipset escape area. The amount of the trace that is over the void should be minimized in the length and percentage of the width of the trace. At worst, no more than half of the trace width should be over the via anti-pad at any given time.
 - If crossing a plane split is necessary, proper placement of stitching caps can minimize the adverse effects on EMI and signal quality performance caused by crossing the split. Stitching capacitors are small-valued capacitors (1 μ F or lower in value) that bridge voltage plane splits close to where high-speed signals or clocks cross the plane split. The capacitor ends should tie to each plane separated by the split. They are also used to bridge, or bypass, power and ground planes close to where a high-speed signal changes layers.
 - As an example of bridging plane splits, a plane split that separates V_{5REF} and V_{CC3_3} planes should have a stitching cap placed near any high-speed signal crossing. One side of the cap should tie to V_{5REF} and the other side should tie to V_{CC3_3} . Stitching caps provide a high frequency current return path across plane splits. They minimize the impedance discontinuity and current loop area that crossing a plane split creates. *Do avoid this scenario, as capacitors stitching on bridging plane splits may only help if both the power planes are not noisy. It is harmful if one of or both the power planes is noisy.*

3.5.2.1 Option 1

This is the most preferred Design option:

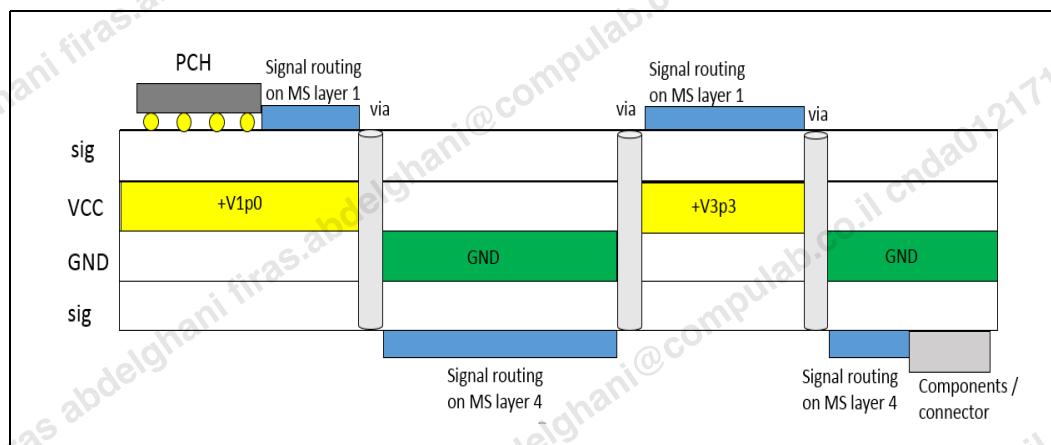
- Reference all signals routing to a solid ground plane that is continuous over the length of the interconnect. This is important especially for high speed differential signals e.g. DMI, PEG, DDI, PCIe3, etc. Specific requirements may be defined within the interface design guideline chapters.
- Differential signals should not cross any plane splits or voids. However, it may be necessary for a trace to be partially routed over a via anti-pad void in the chipset escape area. The amount of the trace that is over the void should be minimized in the length and percentage of the width of the trace. At worst, not more than half of the trace width should be over the via anti-pad at any given time.

- A good plane reference helps to minimize any AC common mode voltage found on the differential-pair as well as benefiting signal quality and minimizing EMI.
- Referencing for signals going over a board-to-board connector must be considered and stitching capacitors should be added at the connector as appropriate. For example, if a differential-pair is GND-referenced on the motherboard and the pair is VCC referenced on the daughter card, then stitching capacitors must be added at the connector between VCC and GND.

3.5.2.2 Option 2

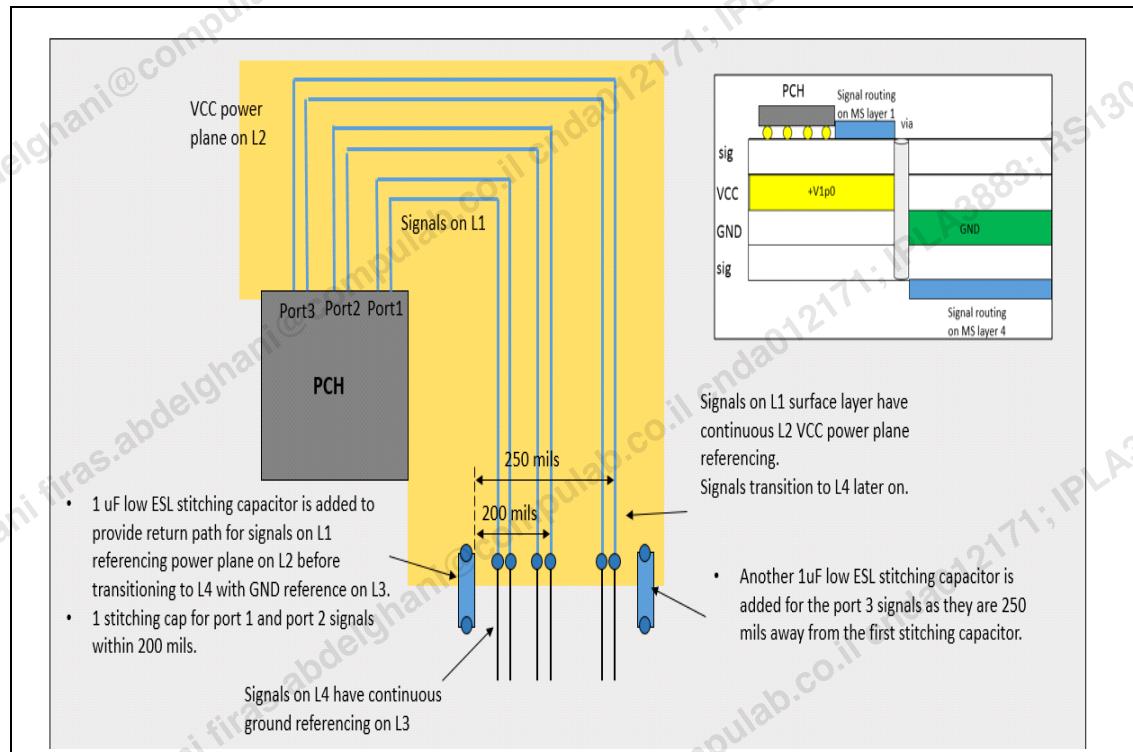
The second preferred design option is for signals to have a solid reference plane (be it VCC or GND) that is continuous over the length of the interconnect. This means that the signals do not route over multiple splits referencing planes in a single layer. An example is shown in [Figure 3-25](#) below.

Figure 3-25. Example - Solid Reference Plane Option



Low ESL stitching capacitor of 1uF should be included to provide a sufficient return path for high speed signals up to 200 mils away. Additional stitching capacitors should be added for additional signals that do not fall within 200 mils of the first stitching capacitor. This is shown in [Figure 3-26](#).

Figure 3-26. Example with Low ESL Stitching Capacitor



Using a continuous power layer as a reference plane is allowed only if the power layer is low noise. This is to avoid the possibility of noise coupling from power to signals.

Signals referencing noisy power planes that are used by switching VRs are not allowed. Route noisy power planes on the same layer as signals to minimize fringe coupling. Do note to implement proper spacing in this case.

3.5.2.3

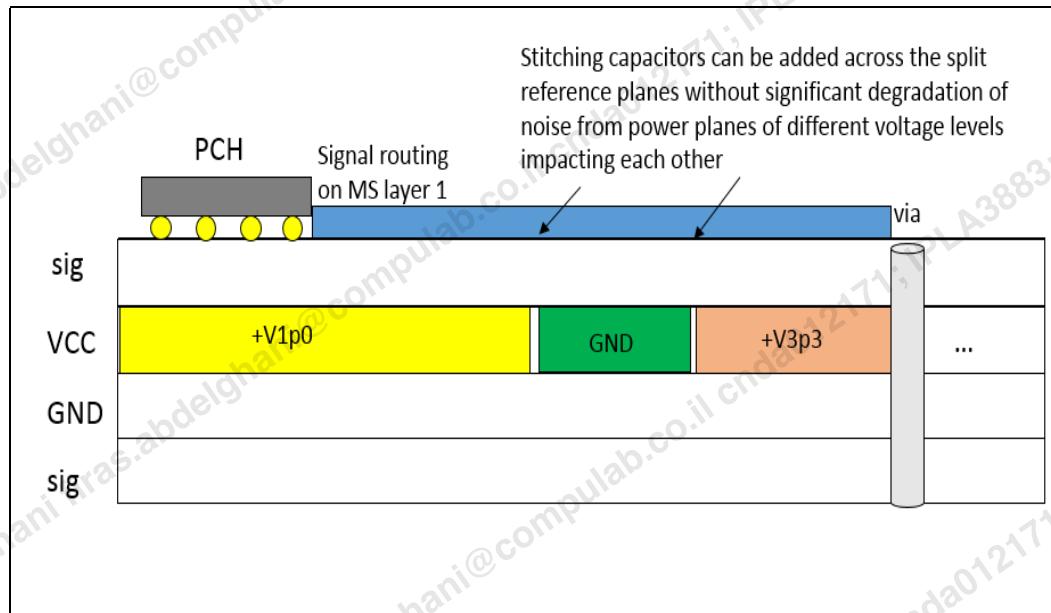
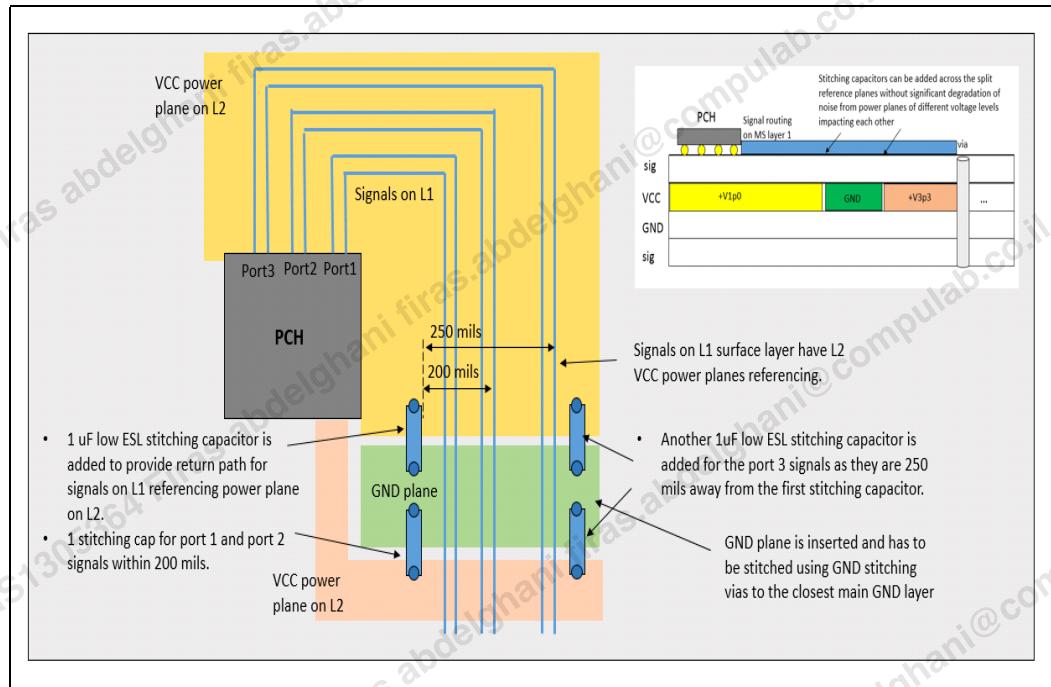
Option 3

If continuous solid plane referencing is unable to be implemented and routing over split planes are unavoidable, the third preferred option is to consider inserting GND planes in between the power planes.

This is to allow for stitching capacitors to be inserted in between the power and ground planes. This option will enable a proper return path for the signals without a significant impact on power integrity.

This option however comes at the cost of a potential added BOM cost.

An example is shown in below figures.

Figure 3-27. Example - Routing over Split Plane

Figure 3-28. Example - Routing Over Split Plane With Low ESL Stitching Capacitor


3.5.2.4

Option 4

The least preferred option is when all the following occurs:

- A solid GND referencing is unavailable.
- A continuous solid plane referencing is unable to be implemented.

- Routing over split planes are unavoidable.
- GND planes are unable to be inserted in between the power planes.

During this case, it is preferable that the power planes crossed by the signals to be of similar voltage levels so as to minimize inter-power plane noise. Stitching capacitors are needed. The capacitor ends should tie to each plane separated by the split.

If the cross plane split occurred between planes of different voltages, then sufficient board decoupling capacitors need to be added to the planes to minimize power integrity noise. Initial recommendation is to include 4 additional capacitors of 1 uF that should be placed within 10mm from the package edge. These should be added in addition to the stitching capacitors requirement.

This option will also come at the cost of a potential added BOM cost.

Examples are shown in below figures.

Figure 3-29. Example - Routing Over Split Plane and GND Planes are Unable to be Inserted

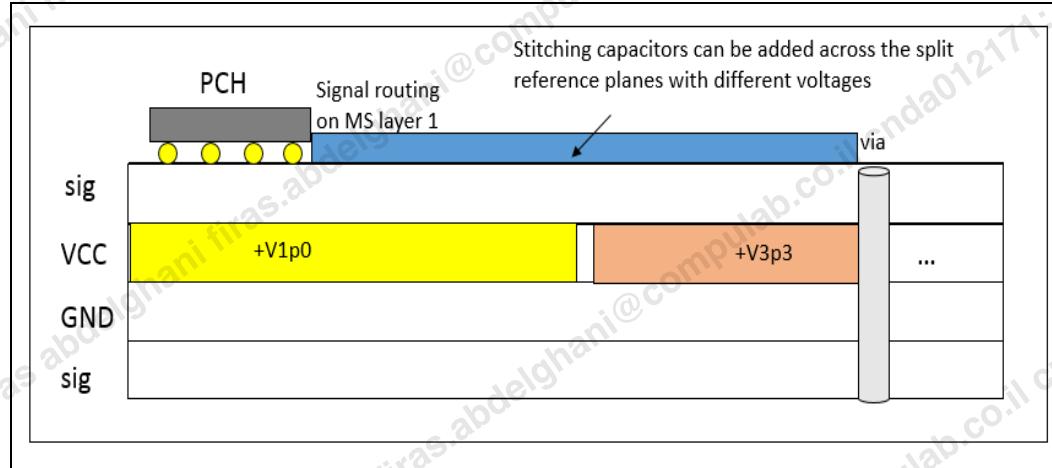
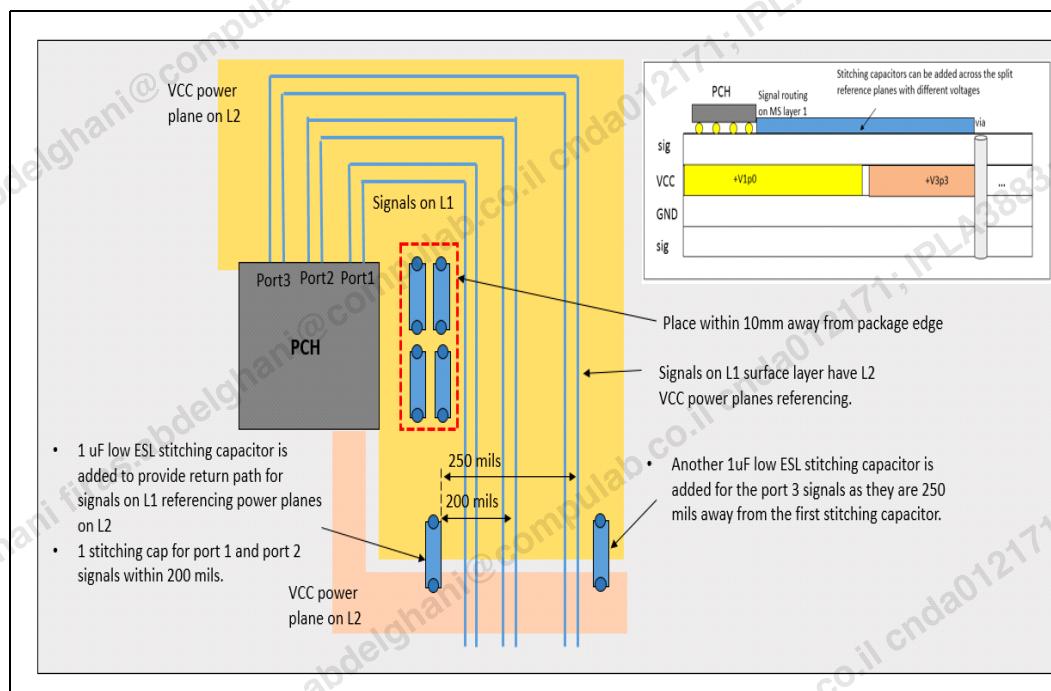


Figure 3-30. Example - Routing Over Split Plane and GND Planes are unable to be Inserted With Low ESL Stitching Capacitor



3.6

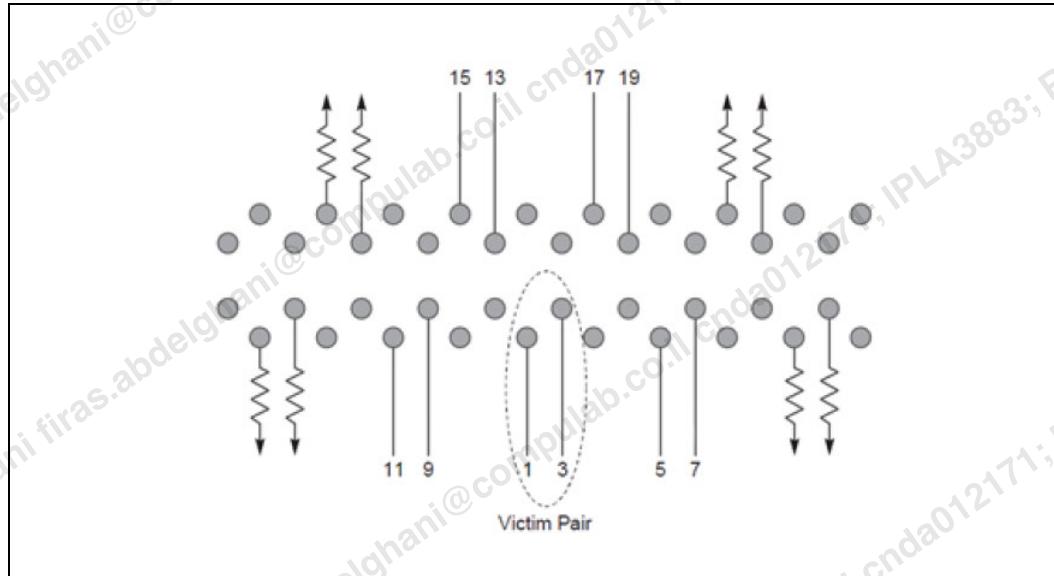
General Docking Connector Recommendations for Differential Interfaces

Although various types and suppliers of docking connectors can be used, Intel recommends following the electrical characteristics in [Table 3-3](#). This table lists the differential insertion loss, return loss, crosstalk, and impedance that Intel assumes



when doing docking topology analysis for all differential interfaces. These are the docking connector electrical characteristics that customers should reference to if customers have routing done within PDG routing guidelines.

Figure 3-31. Example Port A Assignment for Docking Connector



3.7 RCOMP

The RCOMP recommendation for various interfaces provided below

Figure 3-32. RCOMP recommendations

	DDR_RCOMP	PEG_RCOMP	DISP_RCOMP	CFG_RCOMP	PCIE_RCOMP_P/N	USB2_COMP	SD_RCOMP_1P8	SD_RCOMP_3P3	GPPJ_RCOMP_1P8	XCLK_BIASREF	CNV_WT_RCOMP
Board Rterm (ohm)	n/a	24.9Ω +/-1% to VCCIO	24.9Ω +/-1% to VCCIO	49.9Ω +/-1% to GND	100Ω +/-1% Differential	113Ω +/-1% to GND	200Ω +/-1% to GND	200Ω +/-1% to GND	200Ω +/-1% to GND	60Ω +/-1% to GND	150Ω +/-1% to GND
Board Rdc (ohm)	n/a	<0.1	<0.1	<0.5	<0.1	<0.5	<0.1	<0.1	<0.1	<0.5	<0.5
Package Rterm (ohm)	DDR_RCOMP[0]: 121Ω ±1% on pkg to VSS DDR_RCOMP[1]: 75 Ω ±1% on pkg to VSS DDR_RCOMP[2]: 100Ω ±1% on pkg to VSS										
DDR	X										
PEG (CPU)		X									
DMI		X									
HDMI			X								
DP			X								
eDP			X								
CFG				X							
ModPHY					X						
USB2						X					
SD3							X	X			
1.8 GPIO									X		
Differential Clock										X	
CNV_DPHY											X

§ §

**4**

System Memory Interface Design Guidelines

The Coffee Lake platform supports multiple memory technologies. This chapter covers the guidelines to design a Coffee Lake platform with the following Plan of Record (POR) supported system memory interface configurations and features.

Notes:

1. For schematic level and additional system memory signal connection details not covered in this chapter reference the schematic check list chapter.
2. For complete Coffee Lake processor system memory interface POR feature support details see the latest release of the CFL Processor External Design Specification (EDS).

**Table 4-1. System Memory Configurations Supported by Guidelines in this Chapter**

Platform	Config #/ Chapter	Tech	Topology	Freq	Memory Device	Device Ballout	PCB Stackup	IL/ NIL
CFL-H	Chapter 4.1	DDR4	SODIMM + ECC 2DPC	2400	<u>ECC DIMMs:</u> RC-D(1Rx8),RC-G(2Rx8), RC-F(2Rx8),RC-H(2Rx8) <u>Non-ECC DIMMs:</u> RC-A(1Rx8),RC-B(2Rx8), RC-E(2Rx8),RC-C(1Rx16)	260	Type3 - 10L	IL
	Chapter 4.2	DDR4	SODIMM 2DPC	2400	RC-A(1Rx8), RC-B(2Rx8), RC-E(2Rx8),RC-C(1Rx16)	260	Type3 - 8L	IL
	Chapter 4.3	DDR4	SODIMM 1DPC	2400/ 2666	<u>2666:</u> RC-A(1Rx8),RC- E(2Rx8), RC-C(1Rx16) <u>2400:</u> RC-B(2Rx8)	260	Type3 - 8L	IL
	Chapter 4.4	DDR4	SODIMM + ECC 1DPC	2400/ 2666	<u>ECC DIMMs:</u> <u>2666:</u> RC-D(1Rx8),RC-G(2Rx8) <u>2400:</u> RC-H(2Rx8) <u>Non-ECC DIMMs:</u> <u>2666:</u> RC-A(1Rx8),RC-E(2Rx8),RC- C(1Rx16) <u>2400:</u> RC-B(2Rx8)	260	Type3 - 10L	IL
	Chapter 4.5	DDR4	MD 1R x16 (4 per ch) Daisy Chain	2666	SDP x16 DDP x16	96	Type3 - 10L	NIL
	Chapter 4.6	DDR4	MD 2R x8	2666	SDP x8	78	Type3 - 10L	NIL
	Chapter 4.7	DDR4	Mixed SODIMM and MD x16 Daisy- Chain (4 per ch)	2400/ 2666	<u>SODIMM:</u> <u>2666:</u> RC-A(1Rx8),RC-E(2Rx8),RC- C(1Rx16) <u>2400:</u> RC-B(2Rx8) <u>Memory Down:</u> <u>2666:SPD x16</u> <u>2400:DDP x16</u>	SODIMM :260 MDx16: 96	Type3-8L	IL
	Chapter 4.8	DDR4	Mixed SODIMM & MD 1Rx8 Daisy Chain (8 per ch)	2400/ 2666	<u>SODIMM:</u> <u>2666:</u> RC-A(1Rx8),RC-E(2Rx8),RC- C(1Rx16) <u>2400:</u> RC-B(2Rx8) <u>Memory Down:</u> <u>2666:SPD x 8</u>	SODIMM :260 MDx8: 78	Type3-8L	IL
	Chapter 4.9	LPDDR3	MD 2R x32	2133	SDP (1 x 32 die) DDP (2 x 32 dies) QDP (4 x 16 dies)	178	HDI 10L (3-x-3+)	NIL

**Table 4-2. System Memory Interface Guideline Terminology and Descriptions**

CFL Processor and Memory Type	CFL-H			
	DDR4 SO-DIMM+ECC	DDR4 SO-DIMM no ECC	DDR4 Memory Down	LPDDR3 Memory Down
Signal Group Details				
Clock (CLK)	CKN[3:0], CKP[3:0]	CKN[3:0], CKP[3:0]	CKN[1:0], CKP[1:0]	CKP[1:0], CKN[1:0]
Control (CTRL)	CS#[3:0], ODT[3:0]	CS#[3:0], ODT[3:0]	CS#[1:0], ODT[1:0]	CS#[1:0], ODT[0]
Clock Enable (CKE)	CKE[3:0]	CKE[3:0]	CKE[1:0]	CKE[3:0]
Command (CMD)	MA[16:0], BG[1:0], BA[1:0], ACT#, PAR	MA[16:0], BG[1:0], BA[1:0], ACT#, PAR	MA[16:0], BG[1:0], BA[1:0], ACT#, PAR	CAA[9:0], CAB[9:0]
Strobe	DQSP[7:0], DQSN[7:0]	DQSP[7:0], DQSN[7:0]	DQSP[7:0], DQSN[7:0]	DQS[7:0], DQS#[7:0]
ECC strobe	DQSP[8], DQSN[8]	N/A	N/A	N/A
Data	DQ[63:0]	DQ[63:0]	DQ[63:0]	DQ[63:0]
ECC Data	DQ[71:64]	N/A	N/A	N/A
Alert	ALERT#	ALERT#	ALERT#	N/A
Reset	DRAM_RESET#	DRAM_RESET#	DRAM_RESET#	N/A
RCOMP	DDR_RCOMP[2:0]	DDR_RCOMP[2:0]	DDR_RCOMP[2:0]	DDR_RCOMP[2:0]
Guideline Terminology Descriptions				
Via Count	Motherboard Layer Signal Transition Via Placement Locations. At least one ground stitching via must be placed from every signal transition via when ever they change signal layers.			
Diff Spacing	Differential spacing between CK and CK# and between DQS and DQS#			
Group Spacing	Min self spacing and spacing between signals within the same signal group			
Group to Group Spacing	Min spacing between signals from the following different signal groups: [1] CLK-CTRL, CLK-CKE, CLK-CMD, CLK-Reset CTRL-CKE, CTRL-CMD, CTRL-Reset, CKE-CMD, CKE-Reset [2] CLK-Strobe, CLK-Data, CTRL-Strobe, CTRL-Data, CKE-Strobe, CKE-Data, CMD-Strobe, CMD-Data, Reset-Strobe, Reset-Data			
Byte Spacing	[1] Min spacing between strobe and data group signals within the same byte [2] Min spacing between bytes within the same channel and between different channels			
DDR to Other Interfaces/Signals	The minimum spacing requirement for DDR to other signal/interfaces is 25mils.			
DDR Trace impedance and trace geometries	Impedance numbers are calculated according to the stack-up layers thickness, the material conductivity, traces spacing, width and dielectric constant and thickness. The controlling specification is the target trace impedance. It is allowed to change the signal trace width within design tolerance. It is strictly not recommended to reduce spacing between signals. Any spacing reduction can cause to performance degradation.			
Total max length	Total length refers to the signal trace length calculated from Processor die pad to each DRAM ball or each DIMM connector pin Which include Processor inner PKG trace length, Break-out, Main and Break-in trace segments of each DRAM			



4.1 CFL-H DDR4 ECC SO-DIMM 2DPC Guidelines

Table 4-3. System Memory Configuration Details Covered in this Section

Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	Channel A = Two SO-DIMMs with ECC Channel B = Two SO-DIMMs with ECC
Speed (MT/s)	2400
Channels	1 and 2
System Memory Voltage	1.2V
Max Ranks Per Channel	4
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	64
SO-DIMM Raw-Card Types	ECC DIMMs: RC-D(1Rx8),RC-G(2Rx8),RC-F(2Rx8),RC-H(2Rx8) Non-ECC DIMMs: RC-A(1Rx8),RC-B(2Rx8),RC-E(2Rx8)
PCB Layers / Type ¹	10L/T3
DRAM Device Placement	Top & Bottom layers, each channel is dual sided, channels DIMMs placed back-to-back.
Processor Memory Ball Map ²	Interleaved
DRAM Device ODT Capability ³	Enable
Total Max Length	Strobe/Data/CTRL/CLK/CKE/CMD = PKG+BO1+BO2+M+BI RCOMP = M

Notes:

1. Type 3 (T3) = PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias.
Type 4 (T4) (1-x-1+) = PCB with one build-up layer and two layers of Micro-vias.
Type 4 (T4) (2-x-2+) = PCB with two build-up layer and three layers of Micro-vias.
See "Stack-Up and PCB Considerations" chapter for more details in this document.
2. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-by-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
3. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

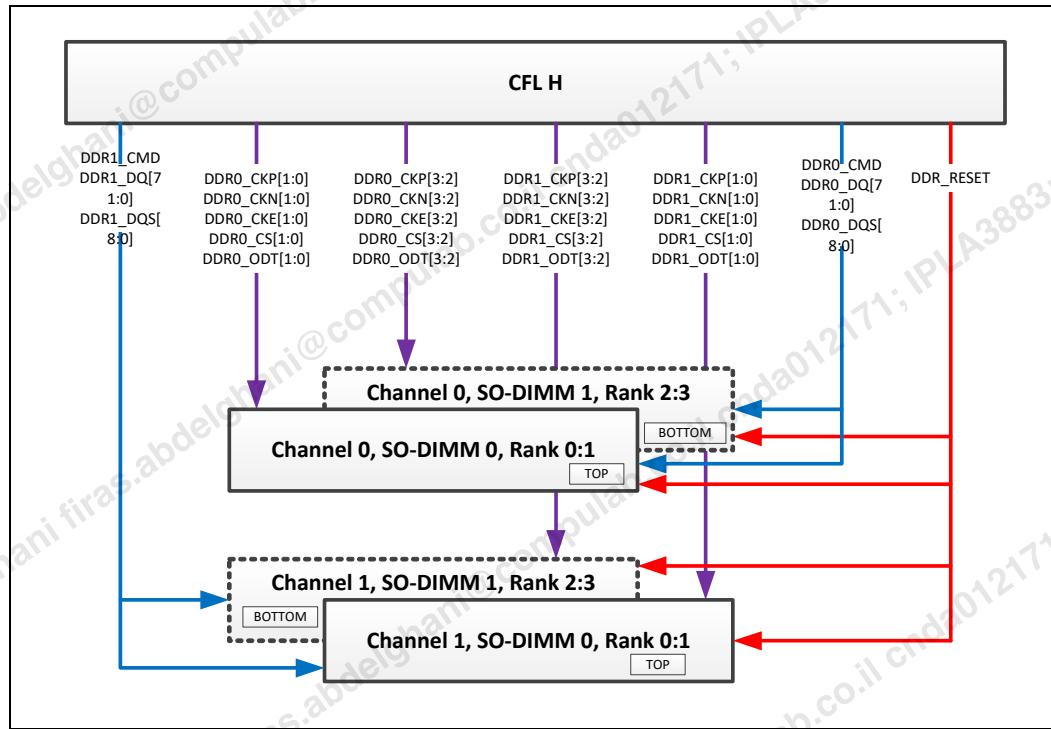
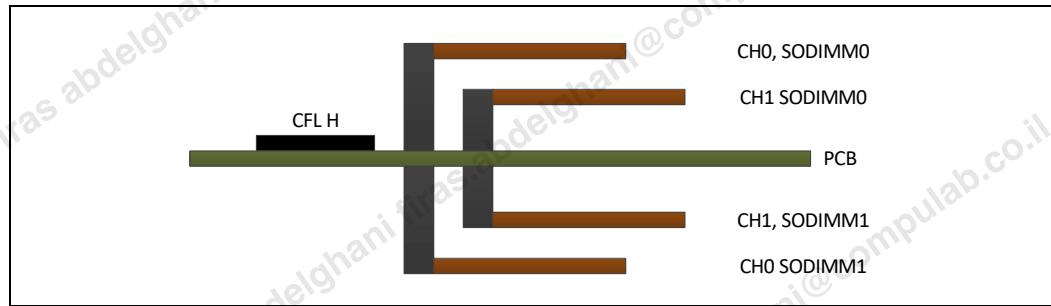
Figure 4-1. CFL-H DDR4 ECC SO-DIMM 2DPC Block Diagram

Figure 4-2. CFL-H DDR4 ECC SO-DIMM 2DPC Block Placement




Figure 4-3. CFL-H DDR4 ECC SO-DIMM 2DPC Signals Topology

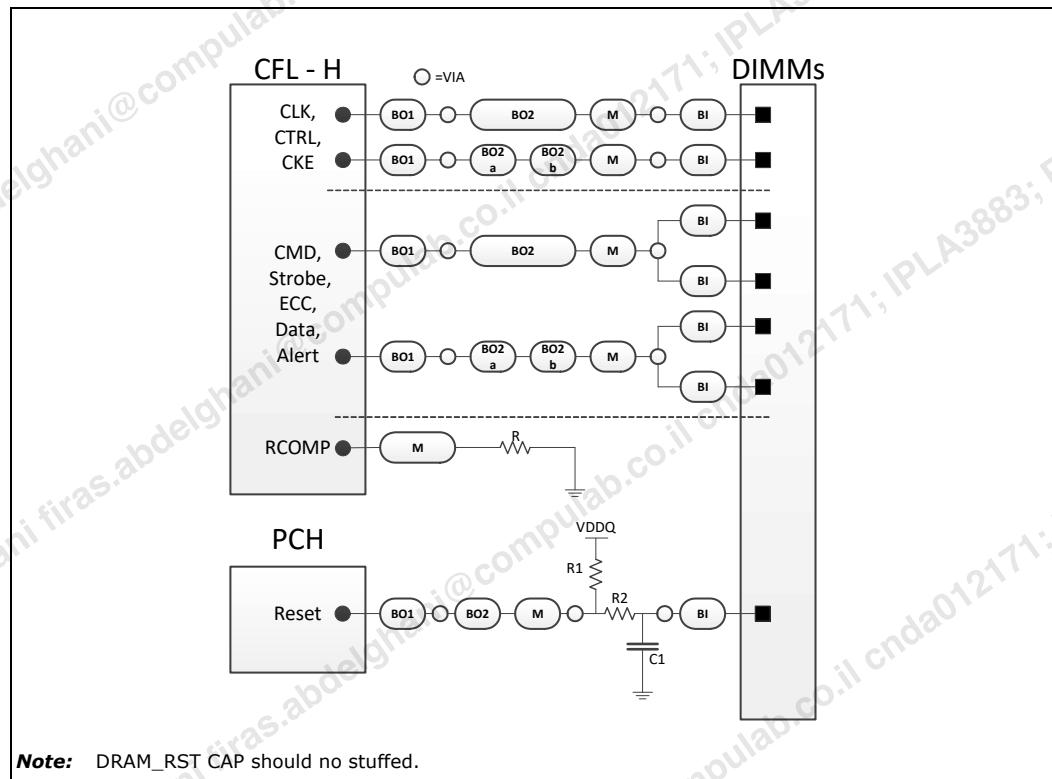


Table 4-4. CFL-H DDR4 ECC SO-DIMM 2DPC Signal Routing Guidelines (Sheet 1 of 4)

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max Length (mils)			Notes	
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1]/[2]	Byte [1]/[2]	Region	Breakout [1,2]	Total	
CLK Channel 0	BO1	MS	VSS/VCC	1	3				3	8	8/		400	[1] 500	4600	1,2, 3,6
	BO2	SL	VSS	0	3				3	8	8/		400			
	M	SL	VSS	0	3.5	88		± 10	3.5	16	20/					
	BI	MS	VSS/VCC	1	4				4	10	10/		300			
CLK Channel 1	BO1	MS	VSS/VCC	1	3				3	5	5/		25	[2] 700	4600	1,2, 3,6
	BO2a	SL	VSS	0	3				3	5	5/		150			
	BO2b	SL	VSS	0	3				3	8	8/		600			
	M	SL	VSS	0	3.5	88		± 10	3.5	16	20/					
	BI	MS	VSS/VCC	1	4				4	10	10/		300			
CTRL CKE Channel 0	BO1	MS	VSS/VCC	1	3				3	5/10			500	[1] 600	4600	1,2, 3
	BO2	SL	VSS	0	3				5	5/10			500			
	M	SL	VSS	0	6	40	± 10		12	12/25						
	BI	MS	VSS/VCC	1	4				4	12/25			300			


Table 4-4. CFL-H DDR4 ECC SO-DIMM 2DPC Signal Routing Guidelines (Sheet 2 of 4)

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)				Max Length (mils)		Notes		
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1]/[2]	Byte [1]/[2]	Region	Breakout [1,2]	Total		
CTRL CKE Channel 1	BO1	MS	VSS/VCC	1	3					3	5/10		25	[2] 700	4600	1,2, 3	
	BO2a	SL	VSS	0	3					3	5/10		150				
	BO2b	SL	VSS	0	3					4	5/10		600	[1] 600	4600		
	M	SL	VSS	0	6	40	± 10			12	12/25						
	BI	MS	VSS/VCC	1	4					4	12/25		300				
CMD Channel 0	BO1	MS	VSS/VCC	1	3					3	5/10		500	[1] 600	4600	1,2, 3,10	
	BO2	SL	VSS	0	3					5	5/10		500				
	M	SL	VSS	0	7.5	35	± 10			13.5	12/25			[2] 700	4600		
	BI	MS	VSS/VCC	1	4					4	12/25		300				
CMD Channel 1	BO1	MS	VSS/VCC	1	3					3	5/10		25	[2] 700	4600	1,2, 3,10	
	BO2a	SL	VSS	0	3					3	5/10		150				
	BO2b	SL	VSS	0	3					4	5/10		600	[1] 700	4600		
	M	SL	VSS	0	7.5	35	± 10			13.5	12/25						
	BI	MS	VSS/VCC	1	4					4	12/25		300				
Strobe Ch0 [7:0]	BO1	MS	VSS	1	3				3		/10	4/25	300	[1] 700	4600	1,2, 3,4, 5,6, 10,1 1	
	BO2	SL	VSS	0	3				3		/10	5/25	650				
	M	SL	VSS	0	5.5	75	± 10	3.5		/25	12/25			[1] 450	4600		
	BI	MS	VSS	1	4				4		/25	8/25	300				
Strobe Ch1 [0]	BO1	MS	VSS	1	3				3		/10	4/25	200	[1] 450	4600	1,2, 3,4, 5,6, 10,1 1	
	BO2	SL	VSS	0	3				3		/10	5/25	350				
	M	SL	VSS	0	5.5	75	± 10	3.5		/25	12/25			[2] 750	4600		
	BI	MS	VSS	1	4				4		/25	8/25	300				
Strobe Ch1[7:1]	BO1	MS	VSS	1	3				3		/10	4/25	25	[2] 750	4600	1,2, 3,4, 5,6, 10,1 1	
	BO2a	SL	VSS	0	3				3		/10	5/25	600				
	BO2b	SL	VSS	0	3				3		/10	5/25	300	[1] 700	4600		
	M	SL	VSS	0	5.5	75	± 10	3.5		/25	12/25						
	BI	MS	VSS	1	4				4		/25	8/25	300				
Data Ch0 Byte [7:0]	BO1	MS	VSS	1	3				3.5	/10	4/25	300	[1] 700	4600	1,2, 3,4, 5,6, 11		
	BO2	SL	VSS	0	3				3	/10	5/25	650					
	M	SL	VSS	0	5.5	42	± 10	9	/25	12/25			[1] 450	4600			
	BI	MS	VSS	1	4				4	/25	5/25	150					
Data Ch1 Byte [0]	BO1	MS	VSS	1	3				3	/10	4/25	200	[1] 450	4600	1,2, 3,4, 5,10 11		
	BO2	SL	VSS	0	3				4.5	/10	5/25	350					
	M	SL	VSS	0	5.5	42	± 10	9	/25	12/25			[2] 750	4600			
	BI	MS	VSS	1	4				4	/25	8/25	150					

**Table 4-4. CFL-H DDR4 ECC SO-DIMM 2DPC Signal Routing Guidelines (Sheet 3 of 4)**

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)				Max Length (mils)			Notes	
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1]/[2]	Byte [1]/[2]	Region	Breakout [1,2]	Total	R ($D \pm 1\%$) C(μF)	
Data Ch1 Byte [7:1]	BO1	MS	VSS	1	3					3	/10	4/25	30	[2] 550 4600	1,2, 3,4, 5,10 ,11		
	BO2a	SL	VSS	0	3					3	/10	5/25	150				
	BO2b	SL	VSS	0	3					5.5	/10	5.5/ 25	500				
	M	SL	VSS	0	5.5		42	± 10		9	/25	12/25					
	BI	MS	VSS	1	4					4	/25	8/25	150				
Strobe Ch0 & Ch1 [8]	BO1	MS	VSS	1	3				3		/10	4/25	200	[1] 450 4600	2,3, 4,5, 6,7, 8,10 ,11		
	BO2	SL	VSS	0	3				3		/10	5/25	350				
	M	SL	VSS	0	6.5	75		± 10	3.5			12/25					
	BI	MS	VSS	1	4				4		/25	8/25	300				
ECC Ch0 & Ch1	BO1	MS	VSS	1	3					3	/10	4/25	200	[1] 450 4600	1,2, 3,4, 5,7, 8,10 ,11		
	BO2	SL	VSS	0	3					4.5	/10	5/25	350				
	M	SL	VSS	0	6.5		42	± 10		9		12/25					
	BI	MS	VSS	1	4					4	/25	8/25	300				
Alert	BO1	MS	VSS/VCC	1	3					3.5	5/10		350	[1] 600 4600	1,2, 3		
	BO2	SL	VSS	0	3.5					4.5	5/10		500				
	M	SL	VSS	0	7.5		35	± 10		13.5	12/25						
	BI	MS	VSS/VCC	1	4					4	12/25		300				
Reset	BO1	MS	VSS/VCC	1	4		50	± 10		4/4		30		8000	(R1) 470 (R2) 0 (C1) 0.1	3,9	
	BO2	MS	VSS/VCC	0	4		50	± 10		4/4							
		SL	VSS	0	3.5		50	± 10		4/4							
	M	MS	VSS/VCC	0	4		50	± 10		4/4							
		SL	VSS	0	3.5		50	± 10		4/4							
RCOMP [0]	M	MS	VSS	2	12-15					20	25/25				500	121	
RCOMP [1]	M	MS	VSS	2	12-15					20	25/25				500	75	
RCOMP [2]	M	MS	VSS	2	12-15					20	25/25				500	100	



Table 4-4. CFL-H DDR4 ECC SO-DIMM 2DPC Signal Routing Guidelines (Sheet 4 of 4)

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max Length (mils)			Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1]/[2]	Byte [1]/[2]	Region	Breakout [1,2]	Total

Note:

- The Channel A CLK/CTRL/CKE/CMD/Strobe/Data/Alert signals all should route on the same inner layer together and they should not route on the same inner layer or an adjacent layer as any of the Channel B CLK/CTRL/CKE/CMD/Strobe/Data/Alert signals. The Channel B CLK/CTRL/CKE/CMD/Strobe/Data/Alert signals all should route on the same inner layer together and they should not route on the same inner layer or an adjacent layer as any of the Channel A CLK/CTRL/CKE/CMD/Strobe/Data/Alert signals. It is possible to spread the routing to another layer as long as the customer meets all impedance and crosstalk parameters in line with other signals which are routed in alternate layers. Within byte signals should be routed in the same layer and channels should be routed in separate layers. Propagation delay matching within groups/bytes should be kept.
- The Max Breakout Length = BO1+BO2 [1] or BO1+(BO2a + BO2b) [2] where specified
- Signals while routed on inner PCB layers must be ground referenced with solid ground floods on both sides.
- The Strobe and Data Group Signals within the same byte must route together for their entire route from CPU Ball to DIMM Pin.
- DQ Bit Swapping is allowed within the same byte, and Byte Swapping is allowed within the same channel. Utilizing this capability enables a modified SO-DIMM pin map and places common SO-DIMM pins in overlapping positions on the top and bottom layers of the motherboard. It also reduces the Data and Strobe signal T-Topology Break-In (BI) segment lengths, it helps eliminate serpentine routing, and creates more room for ground vias next to every Data and Strobe signal transition via in the SO-DIMM pin field area.
- Clock (CLK and CLK#) and Strobe (DQS and DQS#) differential signal swapping within a pair is not allowed. Also differential clock pair to clock pair swapping within a channel is not allowed.
- ECC signals should be routed in separate layer than other DDR (DQ/Strobe/CLK/CTRL/CKE/CMD) signals.
- Parallel routing over ECC signals within DSL layers is not allowed. Vertical routing of low frequency over ECC signals is allowed.
- Capacitor C1 is a defensive design and should be NO STUFF by default.
- Although BI max length is 300 mils, the recommendation is to reduce BI length as possible.
- DQ and DQS signals must route at the same layer and have same width

Table 4-5. CFL-H DDR4 ECC SO-DIMM Length and Matching Guidelines

Signal Group	Rule Details	Length Matching (mils)		Notes
		Min	Max	
CLK	CK[X] - CK#[X], where X = 0 or 1	-5	5	1,2
	CK/CK#[1:0] (max - min)	0	40	1,2
CTRL/CKE	CTRL/CKE (max - min)	0	200	1,2
	CK/CK#[1:0] - CTRL/CKE	0	100	1,2
CMD	CMD (max - min)	0	200	1,2
	CK/CK#[1:0] - CMD	-500	500	1,2
Strobe	DQS[X] - DQS#[X], where X = 0 to 8	-5	5	1,2
	CK/CK#[1:0] - DQS/DQS#[X], where X = 0 to 8	-1500	2500	1,2
Data	DQ(Byte[X]) - DQS/DQS#[X], where X 0 to 7 ECC(7:0) - DQS/DQS#[8]	-20	20	1,2,3

Notes:

- Length Matching = CPU Die to SO-DIMM Pin (PKG + BO1 + BO2 + M + BI, PKG + BO1 + BO2a + BO2b + M + BI); where a conversion factor of 0.9 must be used on Micro-Strip Segments to convert Micro-Strip lengths to Strip-Line equivalent lengths
- To help facilitate and check the Length and Matching relationships on a design please reference the Coffee Lake Platform System Memory Automated Trace Lengths Calculator (ATLC) - #568458
- Byte[0] = DQ[7:0], DQS/DQS#[0], Byte[1] = DQ[15:8], DQS/DQS#[1], Byte[2] = DQ[23:16], DQS/DQS#[2], Byte[3] = DQ[31:24], DQS/DQS#[3], Byte[4] = DQ[39:32], DQS/DQS#[4], Byte[5] = DQ[47:40], DQS/DQS#[5], Byte[6] = DQ[55:48], DQS/DQS#[6], Byte[7] = DQ[63:56], DQS/DQS#[7]



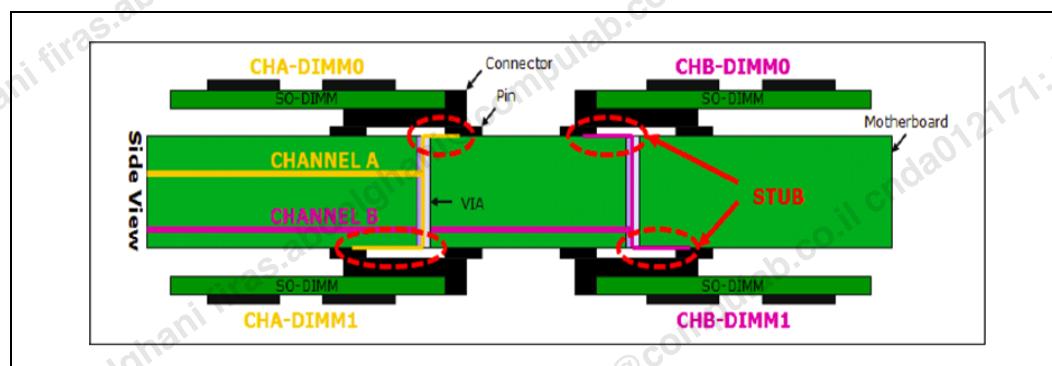
4.1.1

Stub Reduction and Alternative Pin Map

Current SO-DIMM pin assignments are defined by JEDEC spec, same pin assignment is used for both DIMMs. This combination creates stubs of up to 300 mils on the surface routing layers. (See Figure 4-10).

DDR interface allows for data bits to be swizzled within a byte group. Utilizing this capability enables a modified pin map for the second SO-DIMM on each channel that places common pins in overlapping positions on the top and bottom layers of the motherboard. The modified DIMM pin map reduces surface layers stubs on data signals from up to 300 mils to less than 60 mils, resulting in an Eye Width/Eye Height improvement. This modified DIMM pin map also eliminates the need for complex length matching of surface stub lengths and reduces overall routing length of data and strobe signals. This new Pin map allows the data vias to be spaced wider apart, creating space for extra VSS stitching vias and reduction of 3D crosstalk.

Figure 4-4. Stubs on 2 DIMMs Per Channel Configurations



4.2

CFL-H DDR4 SO-DIMM 2DPC Guidelines

Table 4-6. System Memory Configuration Details Covered in this Section (Sheet 1 of 2)

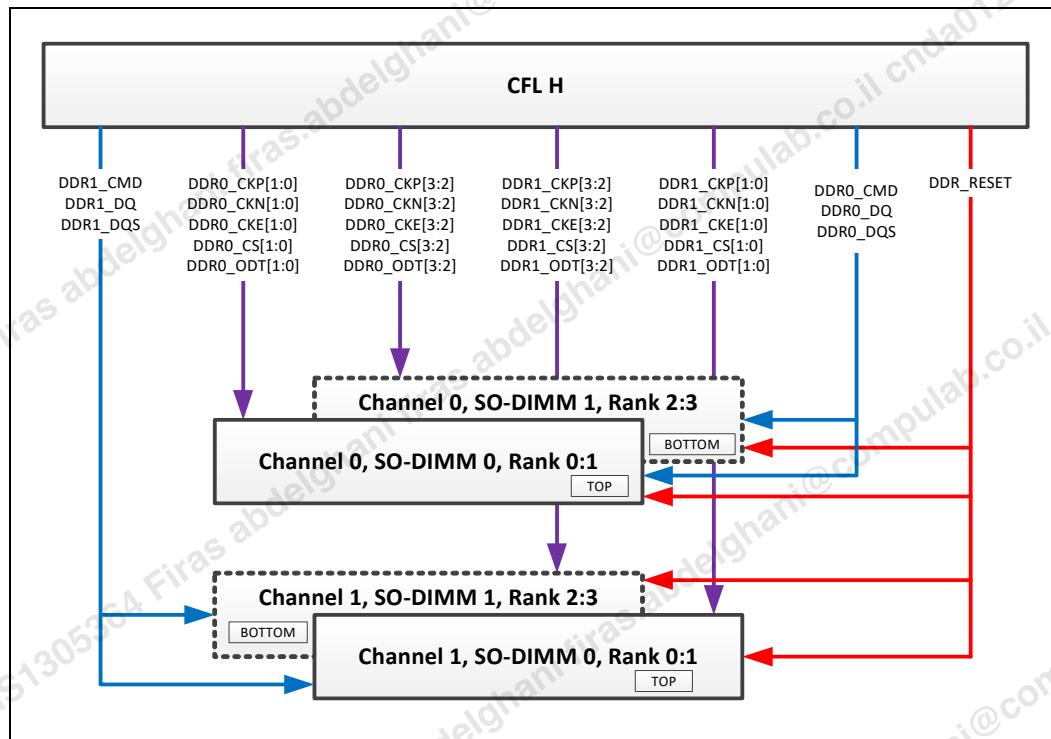
Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	Channel A = Two SO-DIMMs Channel B = Two SO-DIMMs
Speed (MT/s)	2400
Channels	1 and 2
System Memory Voltage	1.2V
Max Ranks Per Channel	4
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	64
SO-DIMM Raw-Card Types	RC-A (1Rx8), RC-B (2Rx8), RC-E(2Rx8)
PCB Layers / Type ¹	8L/T3
DRAM Device Placement	2DPC using T-Topology. SODIMMs connectors on Top & Bottom layers, each channel is dual sided, Channels DIMMs placed back-to-back.

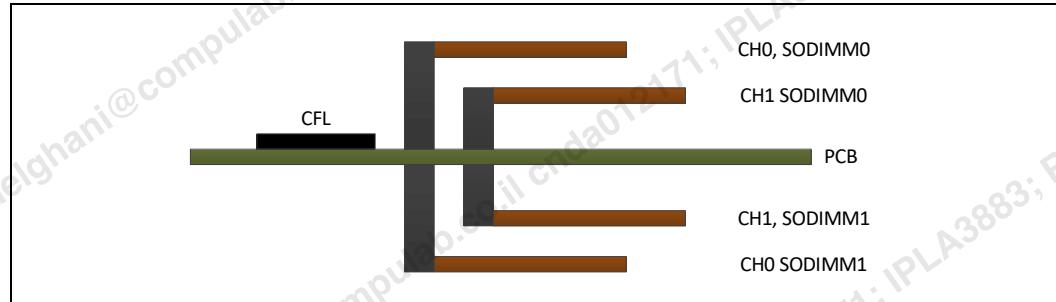
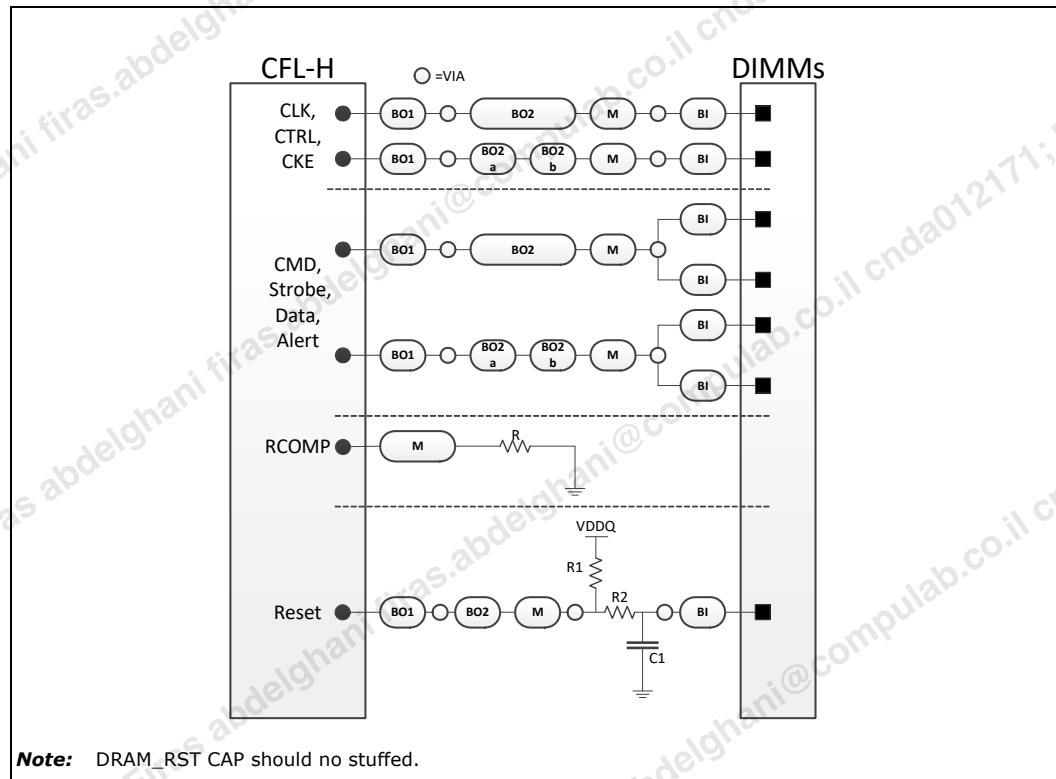
Table 4-6. System Memory Configuration Details Covered in this Section (Sheet 2 of 2)

Parameter	Details
Processor Memory Ball Map ²	Interleaved
DRAM Device ODT Capability ³	Enable
Total Max Length	Strobe/Data/CTRL/CLK/CKE/CMD = PKG+BO1+BO2+M+BI RCOMP = M

Notes:

1. Type 3 (T3) = PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias.
 Type 4 (T4) (1-x-1+) = PCB with one build-up layer and two layers of Micro-vias.
 Type 4 (T4) (2-x-2+) = PCB with two build-up layer and three layers of Micro-vias.
 See "Stack-Up and PCB Considerations" chapter for more details in this document.
2. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-by-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
 Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
3. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

Figure 4-5. CFL-H DDR4 SO-DIMM 2DPC Block Diagram


**Figure 4-6. CFL-H DDR4 SO-DIMM 2DPC Block Placement****Figure 4-7. CFL-H DDR4 SO-DIMM 2DPC Signals Topology**

For CFL-H DDR4 2DPC SODIMM Signals Routing Guidelines table refer to [Table 4-4, "CFL-H DDR4 ECC SO-DIMM 2DPC Signal Routing Guidelines"](#), Please ignore ECC guidelines.

For CFL-H DDR4 2DPC SODIMM Lengths and Matching Guidelines Table refer to [Table 4-5, "CFL-H DDR4 ECC SO-DIMM Length and Matching Guidelines"](#), Please ignore ECC guidelines.



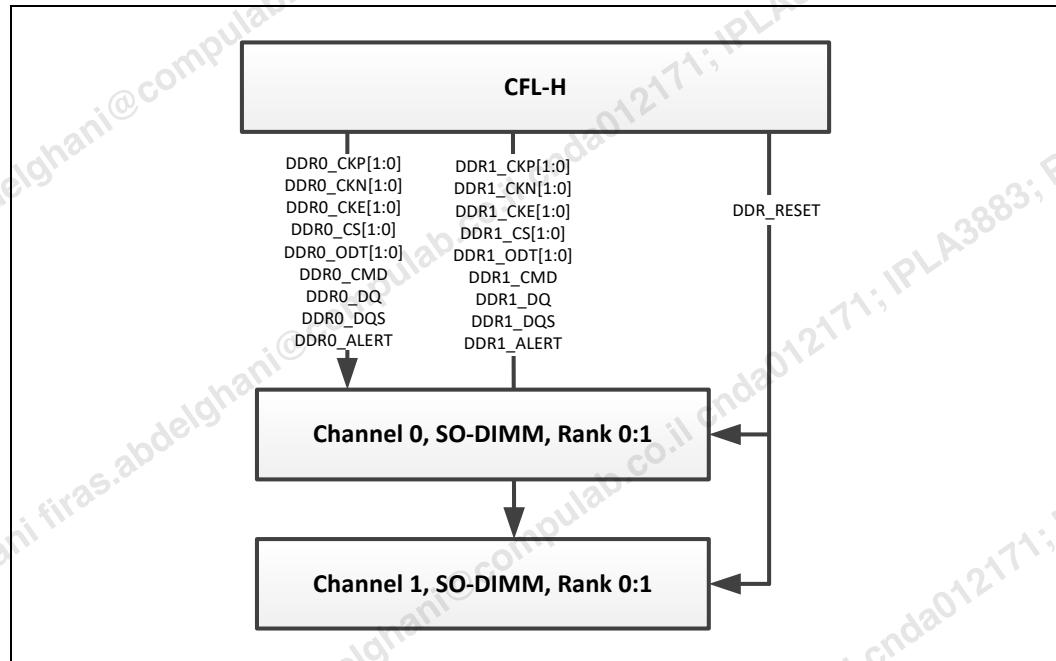
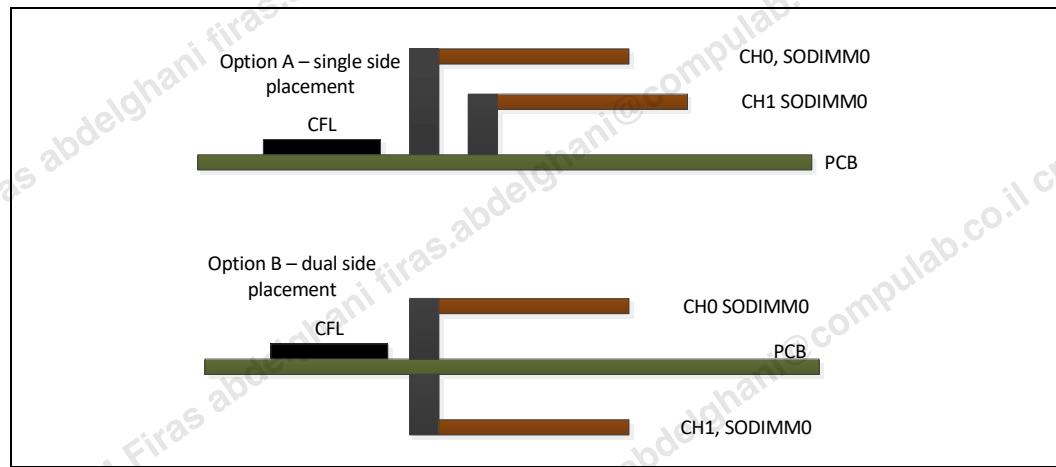
4.3 CFL-H DDR4 SO-DIMM 1DPC Guidelines

Table 4-7. System Memory Configuration Details Covered in this Section

Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	Channel A = One SO-DIMMs Channel B = One SO-DIMMs
Speed (MT/s)	2400/2666
Channels	1 and 2
System Memory Voltage	1.2V
Max Ranks Per Channel	2
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	32
SO-DIMM Raw-Card Types	<u>2666:</u> RC-A (1Rx8), RC-E(2Rx8),RC-C (1Rx16) <u>2400:</u> RC-B (2Rx8)
PCB Layers / Type ¹	8L/T3
DRAM Device Placement	Single side Top layer, OR dual side placement
Processor Memory Ball Map ²	Interleaved
DRAM Device ODT Capability ³	Enable
Total Max Length	Strobe/Data/CTRL/CLK/CKE/CMD = PKG+BO1+BO2+M+BI RCOMP = M

Notes:

1. Type 3 (T3) = PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias.
Type 4 (T4) (1-x-1+) = PCB with one build-up layer and two layers of Micro-vias.
Type 4 (T4) (2-x-2+) = PCB with two build-up layer and three layers of Micro-vias.
See "Stack-Up and PCB Considerations" chapter for more details in this document.
2. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-by-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
3. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

**Figure 4-8. CFL-H DDR4 SO-DIMM 1DPC Block Diagram****Figure 4-9. CFL-H DDR4 SO-DIMM 1DPC Block Placement**

For CFL H DDR4 SO-DIMM 1DPC Signal Topology refer to [Figure 4-7, "CFL-H DDR4 SO-DIMM 2DPC Signals Topology"](#).


Table 4-8. CFL-H DDR4 SO-DIMM 1DPC Signal Routing Guidelines (Sheet 1 of 2)

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)				Max Length (mils)			$R (\Omega \pm 1\%)$	$C (\text{uF})$	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group [1]/[2]	Byte [1]/[2]	Region	Breakout [1,2]	Total			
CLK Channel 0	BO1	MS	VSS/VCC	1	3				3.5	8	8/10		400	[1] 500	4600	1,2, 3,6		
	BO2	SL	VSS	0	3				3	8	8/10		200					
	M	SL	VSS	0	3.5	88		± 10	3.5	16	16/25			300				
	BI	MS	VSS/VCC	1	4				4	16	16/25							
CLK Channel 1	BO1	MS	VSS/VCC	1	3				3.5	8	8/10		25	[1] 620	4600	1,2, 3,6		
	BO2	SL	VSS	0	3				3	8	8/10		610					
	M	SL	VSS	0	3.5	88		± 10	3.5	16	16/25			300				
	BI	MS	VSS/VCC	1	4				4	16	16/25							
CTRL CKE CMD Channel 0	BO1	MS	VSS/VCC	1	3				3.5	5/10			350	[1] 600	4600	1,2, 3		
	BO2	SL	VSS	0	3				5	5/10			500					
	M	SL	VSS	0	6		40	± 10	12	16/25				300				
	BI	MS	VSS/VCC	1	4				4	16/25								
CTRL CKE CMD Channel 1	BO1	MS	VSS/VCC	1	3				3.5	5/10			25	[2] 700	4600	1,2, 3		
	BO2a	SL	VSS	0	3				3	5/10			150					
	BO2b	SL	VSS	0	3				5.5	5/10			600	300				
	M	SL	VSS	0	6		40	± 10	12	16/25								
	BI	MS	VSS/VCC	1	4				4	16/25			300					
Strobe Ch0 [7:0]	BO1	MS	VSS	1	3				3.5		/10	4/25	300	[1] 700	4600	1,2, 3,4, 5,8 6		
	BO2	SL	VSS	0	3				3		/10	5/25	650					
	M	SL	VSS	0	3.5	88		± 10	3.5		/25	16/25		300				
	BI	MS	VSS	1	4				4		/25	5/25	300					
Strobe Ch1 [0]	BO1	MS	VSS	1	3				3.5		/10	4/25	300	[1] 450	4600	1,2, 3,4, 5,6, 8		
	BO2	SL	VSS	0	3				3		/10	5/25	350					
	M	SL	VSS	0	3.5	88		± 10	3.5		/25	16/25		300				
	BI	MS	VSS	1	4				4		/25	5/25	300					
Strobe Ch1 [7:1]	BO1	MS	VSS	1	3				3.5		/10	4/25	25	[2] 750	4600	1,2, 3,4, 5,6, 8		
	BO2a	SL	VSS	0	3				3		/10	5/25	600					
	BO2b	SL	VSS	0	3				3		/10	5/25	300	300				
	M	SL	VSS	0	3.5	88		± 10	3.5		/25	16/25						
	BI	MS	VSS	1	4				4		/25	5/25	300					
Data Ch0 Byte [7:0]	BO1	MS	VSS	1	3				3.5		/10	4/25	300	[1] 700	4600	1,2, 3,4, 5,8		
	BO2	SL	VSS	0	3				3		/10	5/25	650					
	M	SL	VSS	0	3.5	88		± 10	3.5		/25	16/25		300				
	BI	MS	VSS	1	4				4		/25	5/25	300					
Data Ch1 Byte [0]	BO1	MS	VSS	1	3				3.5		/10	4/25	300	[1] 450	4600	1,2, 3,4, 5,8		
	BO2	SL	VSS	0	3				4.5		/10	5/25	350					
	M	SL	VSS	0	3.5	88		± 10	8		/25	16/25		300				
	BI	MS	VSS	1	4				4		/25	5/25	300					

**Table 4-8. CFL-H DDR4 SO-DIMM 1DPC Signal Routing Guidelines (Sheet 2 of 2)**

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)				Max Length (mils)			R ($D \pm 1\%$) C(μF)	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1]/[2]	Byte [1]/[2]	Region	Breakout [1,2]	Total		
Data Ch1 Byte [7:1]	BO1	MS	VSS	1	3					3.5	/10	4/25	25	[2] 750	4600	1,2, 3,4, 5,8	
	BO2a	SL	VSS	0	3					3	/10	5/25	600				
	BO2b	SL	VSS	0	3					5.5	/10	5.5/25	300				
	M	SL	VSS	0	3.5	50	± 10			8	/25	16/25					
	BI	MS	VSS	1	4					4	/25	5/25	300				
Alert	BO1	MS	VSS/VCC	1	3					3.5	5/10		30	[2] 750	4600	1,2, 3,	
	BO2a	SL	VSS	0	3					3	5/10		500				
	BO2b	SL	VSS	0	3.5					5	5/10		200				
	M	SL	VSS	0	6	40	± 10			12	16/25						
	BI	MS	VSS/VCC	1	4					4	16/25		300				
Reset	BO1	MS	VSS/VCC	1	4	50	± 10			4/4			30	1000	8000	(R1) 470 (R2) 0 (C1) 0.1	
	BO2	MS	VSS/VCC	0	4	50	± 10			4/4							
		SL	VSS	0	3.5	50	± 10			4/4							
	M	MS	VSS/VCC	0	4	50	± 10			4/4							
		SL	VSS	0	3.5	50	± 10			4/4							
	BI	MS	VSS/VCC	1	4	50	± 10			4/4							
RCOMP [0]	M	MS	VSS	2	12-15				20	25/25					500	121	
RCOMP [1]	M	MS	VSS	2	12-15				20	25/25					500	75	
RCOMP [2]	M	MS	VSS	2	12-15				20	25/25					500	100	

Notes:

- The Channel A CLK/CTRL/CKE/CMD/Strobe/Data signals all must route on the same inner layer together and they must not route on the same inner layer or an adjacent layer as any of the Channel B CLK/CTRL/CKE/CMD/Strobe/Data signals. The Channel B CLK/CTRL/CKE/CMD/Strobe/Data signals all must route on the same inner layer together and they must not route on the same inner layer or an adjacent layer as any of the Channel A CLK/CTRL/CKE/CMD/Strobe/Data signals.
- The Max Breakout Length = BO1+BO2 [1] or BO1+(BO2a + BO2b) [2] where specified
- Signals while routed on inner PCB layers must be ground referenced with solid ground floods on both sides.
- The Strobe and Data Group Signals within the same byte must route together for their entire route from CPU Ball to DIMM Pin.
- DQ Bit Swapping is allowed within the same byte, and Byte Swapping is allowed within the same channel. Utilizing this capability enables a modified SO-DIMM pin map and places common SO-DIMM pins in overlapping positions on the top and bottom layers of the motherboard. It also reduces the Data and Strobe signal T-Topology Break-In (BI) segment lengths, it helps eliminate serpentine routing, and creates more room for ground vias next to every Data and Strobe signal transition via in the SO-DIMM pin field area.
- Clock (CLK and CLK#) and Strobe (DQS and DQS#) differential signal swapping within a pair is not allowed. Also differential clock pair to clock pair swapping within a channel is not allowed.



7. Capacitor C1 is a defensive design and should be NO STUFF by default
8. DQ and DQS signals must route at the same layer and have same width

For CFL-H DDR4 SO-DIMM Length and Matching Guidelines refer to Table 4-5, "CFL-H DDR4 ECC SO-DIMM Length and Matching Guidelines".



4.4

CFL H DDR4 ECC SO-DIMM 1DPC guidelines

Table 4-9. System Memory Configuration Details Covered in this Section

Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	Channel A = One SO-DIMMs Channel B = One SO-DIMMs
Speed (MT/s)	2400/2666
Channels	1 and 2
System Memory Voltage	1.2V
Max Ranks Per Channel	2
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	32
SO-DIMM Raw-Card Types	ECC DIMMs: <u>2666</u> : RC-D(1Rx8), RC-G(2Rx8), RC-F(2Rx8) <u>2400</u> : RC-H(2Rx8) Non-ECC DIMMs: <u>2666</u> : RC-A(1Rx8), RC-E(2Rx8), RC-C (1Rx16) <u>2400</u> : RC-B(2Rx8)
PCB Layers / Type ¹	10L/T3
DRAM Device Placement	Single side Top layer, OR dual side placement
Processor Memory Ball Map ²	Interleaved
DRAM Device ODT Capability ³	Enable
Total Max Length	Strobe/Data/CTRL/CLK/CKE/CMD = PKG+BO1+BO2+M+BI RCOMP = M

Notes:

1. Type 3 (T3)= PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias.
Type 4 (T4) (1-x-1+) = PCB with one build-up layer and two layers of Micro-vias.
Type 4 (T4) (2-x-2+) = PCB with two build-up layer and three layers of Micro-vias.
See "Stack-Up and PCB Considerations" chapter for more details in this document.
2. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-by-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
3. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

For all signals, exclude ECC, please follow Chapter 4, "CFL-H DDR4 SO-DIMM 1DPC Guidelines".

ECC guidelines are similar to DQ/DQS in Chapter 4, "CFL-H DDR4 SO-DIMM 1DPC Guidelines".



ECC signals to be routed at separated layer than other DDR signals.

For CFL-H DDR4 1DPC ECC SODIMM Lengths and Matching Guidelines Table refer to [Table 4-5, "CFL-H DDR4 ECC SO-DIMM Length and Matching Guidelines"](#), Please ignore ECC guidelines.



4.5

CFL-H DDR4 1R x16 Memory Down Guidelines

Table 4-10. System Memory Configuration Details Covered in this Section

Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	Channel A = x16 Memory Down (4 DRAM Devices) Channel B = x16 Memory Down (4 DRAM Devices)
Speed (MT/s)	2666
Channels	1 and 2
System Memory Voltage	1.2V
Max Ranks Per Channel	1
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	SDP - 8 DDP - 16
Memory Down Types ^{1 2} (Pkg Ranks - Die Bits - Pkg bits)	96-Ball BGA SDP 1-16-16 DDP 1-8-16 Not for a common SDP/DDP board
PCB Layers / Type ³	10L/T3
DRAM Device Placement	Each Channel is Single Sided, Channels are Side by Side Placement
CPU System Memory Ball Map ⁴	Non-Interleaved
DRAM Device ODT Capability ⁵	Enabled
Total Max Length	Strobe/Data/Reset = PKG+BO+M+BI CLK/CTRL/CKE/CMD= PKG+BO+M+BI1+BI2 RCOMP = M

Notes:

1. SDP: Single Die Package, DDP: Dual Die Package
2. No mixed vendor support within a channel or channel to channel and No mixed memory DRAM down type support (SDP, DDP) within a channel or channel to channel
3. Type 3 = PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias. See "Stack-Up and PCB Considerations" chapter for more details.
4. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-By-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
5. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

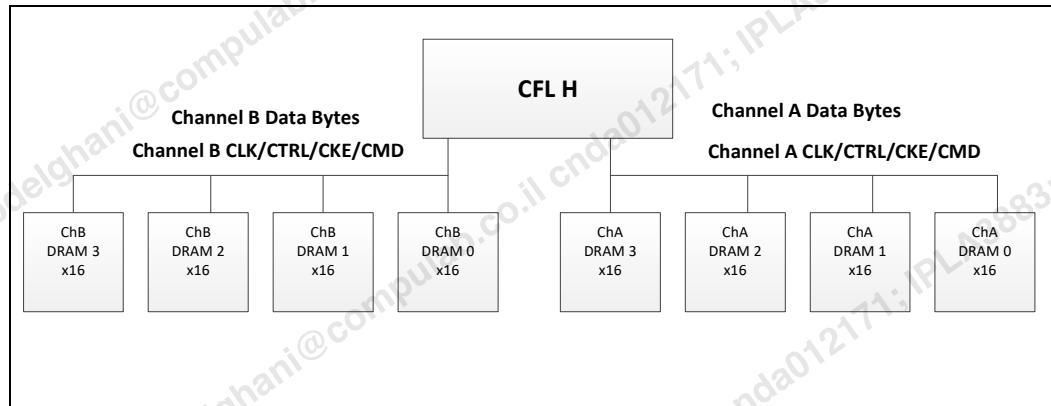
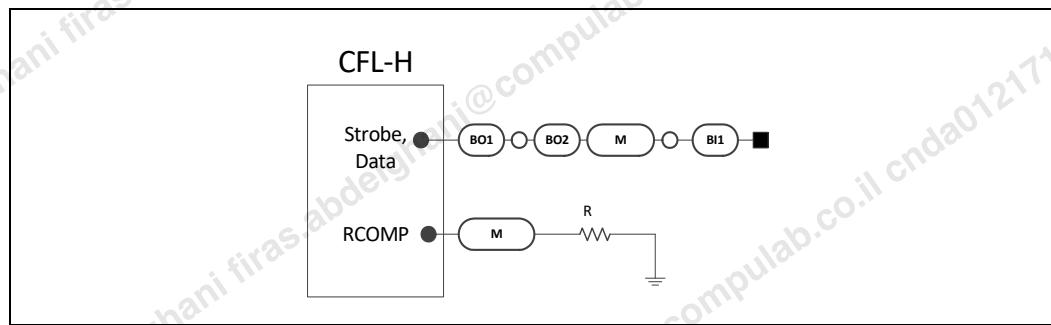
Figure 4-10. CFL-H DDR4 1Rx16 Memory Down Placement and Block Diagram

Figure 4-11. CFL-H DDR4 1Rx16 Memory Down Strobe/Data/RCOMP Signal Topologies




Figure 4-12. CFL-H DDR4 1Rx16 Memory Down CLK/CTRL/CKE/CMD/Reset Signal Topology

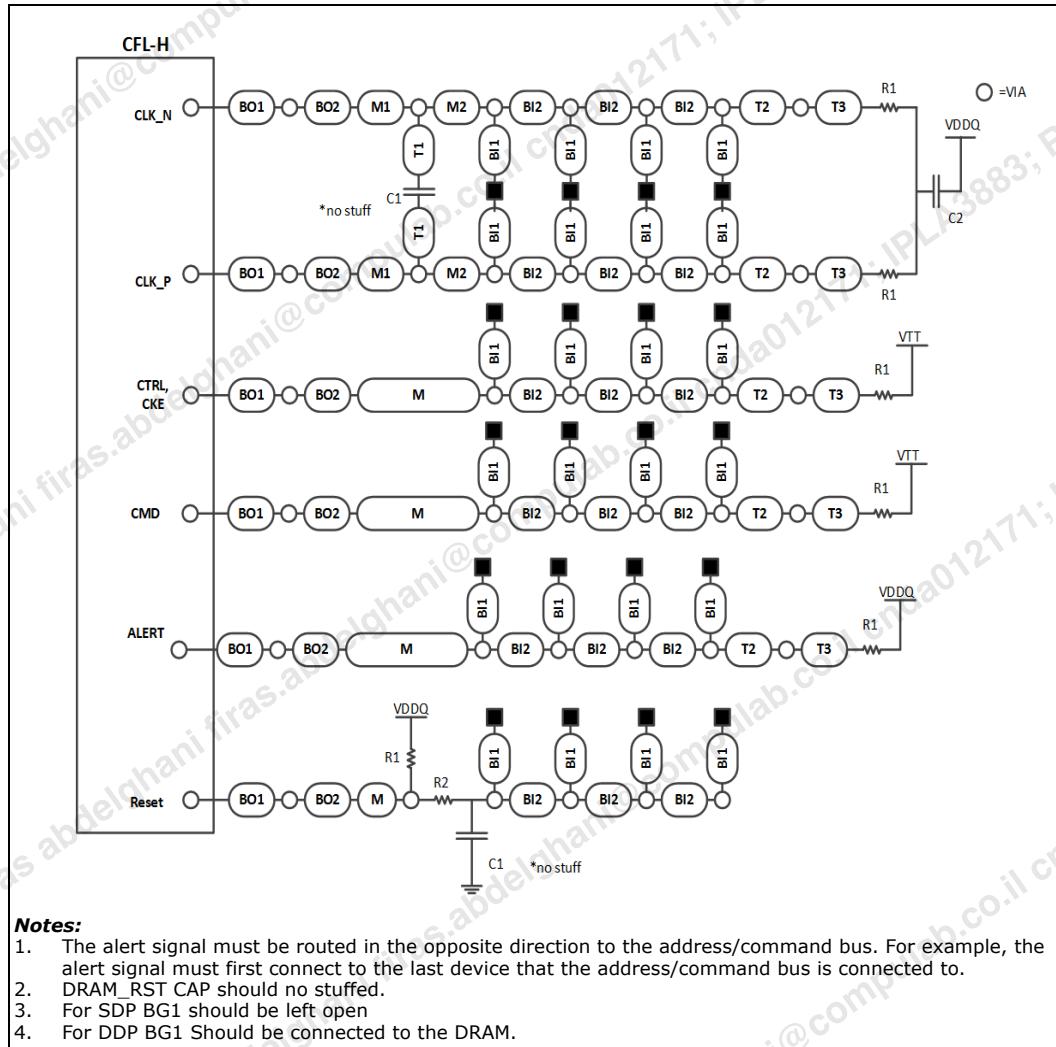



Table 4-11. CFL-H DDR4 1Rx16 Memory Down Routing Guideline (Sheet 1 of 3)

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max (mils) Length			R ($\Omega \pm 1\%$) C(μF)	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1&2]	Byte [1&2]	Region	Breakout	Total	
CLK	BO1	MS	VSS	1	3				3.5	3.5	3.5		450	800	(R1) 36 (C1-no stuff) 0.0033 (C2) 0.01	1,2, 3, 7,8
	BO2	SL	VSS	0	3.5				4	16	16		700			
	M1	SL	VSS	0	6/6.5	72	40	± 10	4.5	16	16					
	M2	SL	VSS	0	5/5.5				4.5/ 4	16	16		1000			
	BI1	SL	VSS	8	3				3.5	16	16		150			
	BI2	SL	VSS	0	4.5	85		± 10	4.5	16	16		700			
	T1	MS	VSS	1	3				3.5	16	16		200			
	T2	SL	VSS	0	4.5	85		± 10	4.5	16	16		300			
	T3	MS	VSS	1	3				3.5	16	16		50			
CTRL/ CKE	BO1	MS	VSS	1	3					3.5	3.5		450	800	36	1,2, 3
	BO2	SL	VSS	0	3.5					4	16		700			
	M	SL	VSS	0	5.5/7		40	± 10		5/6	16					
	BI1	MS	VSS	8	3					3.5	16		150			
	BI2	SL	VSS	0	4.5		50	± 10		6.5	16		700			
	T2	SL	VSS	0	4.5		50	± 10		6.5	16		300			
	T3	MS	VSS	1	3					3.5	16		50			
CMD	BO1	MS	VSS	1	3					3.5	3.5		450	800	36	1,2, 3
	BO2	SL	VSS	0	3.5					4	16		700			
	M	SL	VSS	0	5.5/7		40	± 10		4.5/ 5.5	16					
	BI1	MS	VSS	8	3					3.5	16		150			
	BI2	SL	VSS	0	4.5		50	± 10		6.5	16		700			
	T2	SL	VSS	0	4.5		50	± 10		6.5	16		300			
	T3	MS	VSS	1	3					3.5	16		50			

**Table 4-11. CFL-H DDR4 1Rx16 Memory Down Routing Guideline (Sheet 2 of 3)**

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max (mils) Length			R ($\Omega \pm 1\%$)	C (pF)	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group[1&2]	Byte [1&2]	Region	Breakout	Total		
Strobe	BO1	MS	VSS	1	3				3.5		3.5	3.5	450	800	4500	1,2, 4,5, 6,7, 9,10	
	BO2	SL	VSS	0	3.5				4		16	25	700				
	M	SL	VSS	0	4/4.5	85		± 10	4.5		16	25					
	BI1	SL	VSS	1	3				3.5		16	25	150				
Data	BO1	MS	VSS	1	3					3.5	3.5	3.5	450	800	4500	1,2, 4,5, 6,9, 10	
	BO2	SL	VSS	0	3.5					4	16	25	700				
	M	SL	VSS	0	4/4.5		50	± 10		4.5/ 5.5	16	25					
	BI1	SL	VSS	1	3					3.5	16	25	150				
Alert	BO1	MS	VSS	1	3					3.5	3.5		450	800	[1st] 6000 [Last] 8000 (R1 connected to VDDQ) 50	1,2, 3	
	BO2	SL	VSS	0	3.5					4	16		700				
	M	SL	VSS	0	4/4.5		50	± 10		4.5/ 5.5	16						
	BI1	MS	VSS	0	3					3.5	16		150				
	BI2	SL	VSS	0	4.5		50	± 10		6.5	16		700				
	T2	SL	VSS	0	4.5		50	± 10		6.5	16		300				
	T3	MS	VSS	1	3					3.5	16		50				
Reset	BO1	MS	VSS	1	3						3.5		30	1000	8000 (R1) 470 (R2) 0 (C1) 0.1	3,8	
	BO2	SL	VSS	0	3.5						20		1000				
	M	SL	VSS	1	4/4.5		50	± 10			20						
	BI1	MS	VSS	8	3						20						
	BI2	MS	VSS	0	4.5		50	± 10			20						
RCOMP [0]	M	MS	VSS	4	12-15					13	13		500	500	121	12	
RCOMP [1]	M	MS	VSS	4	12-15					13	13		500	500	121	13	
RCOMP [2]	M	MS	VSS	4	12-15					13	13		500	500	100		

**Table 4-11. CFL-H DDR4 1Rx16 Memory Down Routing Guideline (Sheet 3 of 3)**

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max (mils) Length			R ($\Omega \pm 1\%$)	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group[1&2]	Byte [1&2]	Region	Breakout	Total	

Notes:

- Avoid any parallel routing between two adjacent layers. When parallel routing can not be avoided in the CPU Break Out, it is recommended to offset the signals from two adjacent layers so no direct overlap occurs. If needed, the total parallel routing length in the CPU Break Out, which includes both overlapped and offset parallel routing, must be 300 mils or less.
- Signals while routed on inner PCB layers must be ground referenced with solid ground floods on both sides.
- Use individual termination resistors (R1) for each signal. Don't use Rpacks
- For Option #1 (Single Rank) configuration there are only 8 DRAM Devices connected to each CMD Group Signal and only 1 DRAM Device connected to each Strobe/Data Group Signal. For these designs DRAM Devices [15:8] and their corresponding BI1 routing segments need to be removed for each CMD Group Signal and the second DRAM Device and corresponding BI routing segment needs to be removed for each Strobe/Data Group Signal.
- The Strobe and Data Group Signals within the same byte must always route together on the same layers for their entire route
- DQ Bit Swapping is allowed within the same byte, and Byte Swapping is allowed within the same channel
- Clock (CLK and CLK#) and Strobe (DQS and DQS#) differential signal swapping within a pair is not allowed
- Capacitor C1 is a defensive design and should be NO STUFF by default
- DQ and DQS signals must route at the same layer and have same width
- Route 2 adjacent bytes to same DRAM device - like DRAM0(BYTE0,1) DRAM1 (BYTE 2,3),, for better VREF training per DRAM device.
- Impedance numbers are for reference only, it is calculating according to the stackup layers thickness, the material conductivity, traces spacing and width. The recommendation is to follow stackup and traces geometries.
- RCOMP[1] value for Mix SoDIMM and MD topology should be 75 Ohm

Table 4-12. CFL-H DDR4 1Rx16 Memory Down Length Matching Guidelines (Sheet 1 of 2)

Signal Group	Rule Details	Length Matching (mils)		Notes
		Min	Max	
CLK	BI1 (max - min)	0	50	2
	CK[X] - CK#[X]; where X = 0 or 1	-5	5	1,2
	CK/CK#[1:0] (max - min)	0	10	1,2
CTRL/CKE	BI1 (max - min)	0	0	2,4
	CTRL/CKE (max - min)	0	100	1,2
	CK/CK#[X] - CTRL/CKE; where X = 0 or 1	0	100	1,2,6
CMD	BI1 (max - min)	0	0	2,4
	CMD (max - min)	0	100	1,2
	CK/CK#[0] - CMD; where X = 0 or 1	-500	500	1,2,6
Strobe	BI1 (max - min)	0	0	2,5
	DQS[X] - DQS#[X], where X = 0 to 7	-5	5	1,2
	CK/CK#[X] - DQS/DQS#[Y], where X = 0 or 1 and Y = 0 to 7	-500	3500	1,2
Data	BI(max-min)	0	0	2,5
	DQ(Byte[X]) - DQS/DQS#[X], where X = 0 to 7	-20	20	1,2,3

**Table 4-12. CFL-H DDR4 1Rx16 Memory Down Length Matching Guidelines (Sheet 2 of 2)****Notes:**

1. Length Matching = CPU Die to DRAM Ball of every DRAM Device (CLK = PKG+BO1+BO2+M1+M2+BI1+BI2, CTRL/CKE/CMD = PKG+BO1+BO2+M+BI1+BI2, Strobe/Data = PKG+BO1+BO2+M+BI1); where a conversion factor of 0.9 must be used on Micro-Strip Segments to convert Micro-Strip lengths to Strip-Line equivalent lengths
2. To help facilitate and check the Length and Matching relationships on a design please reference the Coffee Lake Platform System Memory Automated Trace Lengths Calculator (ATLC) - #568458
3. Byte[0] = DQ[7:0], DQS/DQS#[0], Byte[1] = DQ[15:8], DQS/DQS#[1], Byte[2] = DQ[23:16], DQS/DQS#[2], Byte[3] = DQ[31:24], DQS/DQS#[3], Byte[4] = DQ[39:32], DQS/DQS#[4], Byte[5] = DQ[47:40], DQS/DQS#[5], Byte[6] = DQ[55:48], DQS/DQS#[6], Byte[7] = DQ[63:56], DQS/DQS#[7]
4. CMD/CTRL BI matching: this matching rule refer to all BI (Break-ins) sections that routed within each signal. For example: ADDR[0]/[1] BI1 should be equal in all DRAMs. ADDR[0] BI1 may be equal to ADDR[1] BI1.
5. DQ/DQS matching rules: DQ - BI should be matched within all bytes and not only within byte (max-min=0). DQ[63..0] BI section should be equal. DQS - BI should be matched within all bytes and not only within bytes (max-min=0). DQS[7..0][P/N] BI section should be equal. DQ and DQS BI does not need to be matched.
6. The delta between CLK signals to CMD/CTRL/CKE, between DRAMs should be kept < 20mils. For exp: |DRAM[x](CK[i]-Addr[j]) - DRAM[y](CK[i]-Addr[j])| < 20mils.

4.6 CFL-H DDR4 2R x8 Memory Down Guidelines

Table 4-13. System Memory Configuration Details Covered in this Section

Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	Channel A = x8 Memory Down (16 DRAM Devices for 2Ranks) Channel B = x8 Memory Down (16 DRAM Devices for 2Ranks)
Speed (MT/s)	2666
Channels	1 and 2
System Memory Voltage	1.2V
Max Ranks Per Channel	2
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	32
Memory Down Types ^{1 2} (Pkg Ranks - Die Bits - Pkg bits)	78-Ball BGA SDP 1-8-8
PCB Layers / Type ³	10L/T3
DRAM Device Placement	Each Channel is Dual Sided, Channels are Side by Side Placement
CPU System Memory Ball Map ⁴	Non-Interleaved
DRAM Device ODT Capability ⁵	Enabled
Total Max Length	Strobe/Data = PKG+BO1+BO2+M+BI1 Reset = PKG+BO1+BO2+M+BI1+BI2 CLK = PKG+BO1+BO2+M1+M2+BI1+BI2 CTRL/CKE/CMD = PKG+BO1+BO2+M+BI1+BI2 RCOMP = M

Notes:

1. SDP: Single Die Package, DDP: Dual Die Package
2. No mixed vendor support within a channel or channel to channel and No mixed memory DRAM down type support (SDP, DDP) within a channel or channel to channel
3. Type 3 = PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias. See "Stack-Up and PCB Considerations" chapter for more details.

4. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-By-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
5. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

Figure 4-13. CFL-H DDR4 x8 Memory Down Placement and Block Diagram

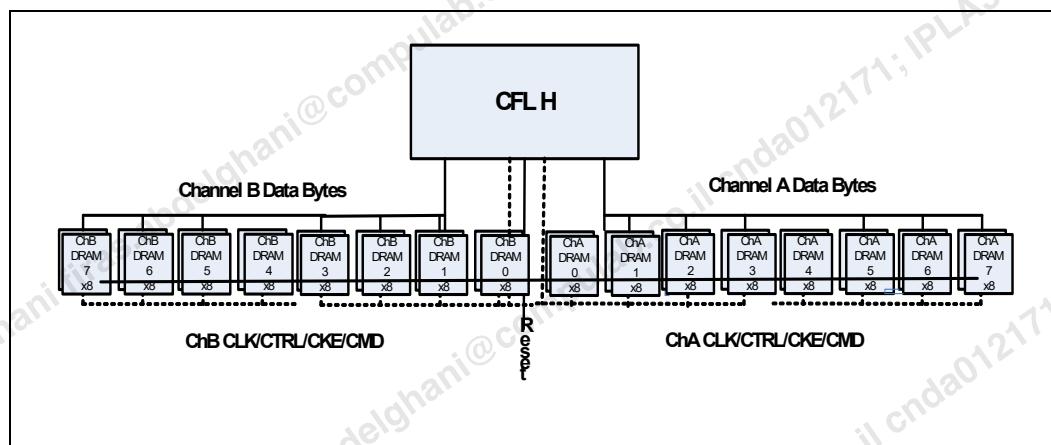
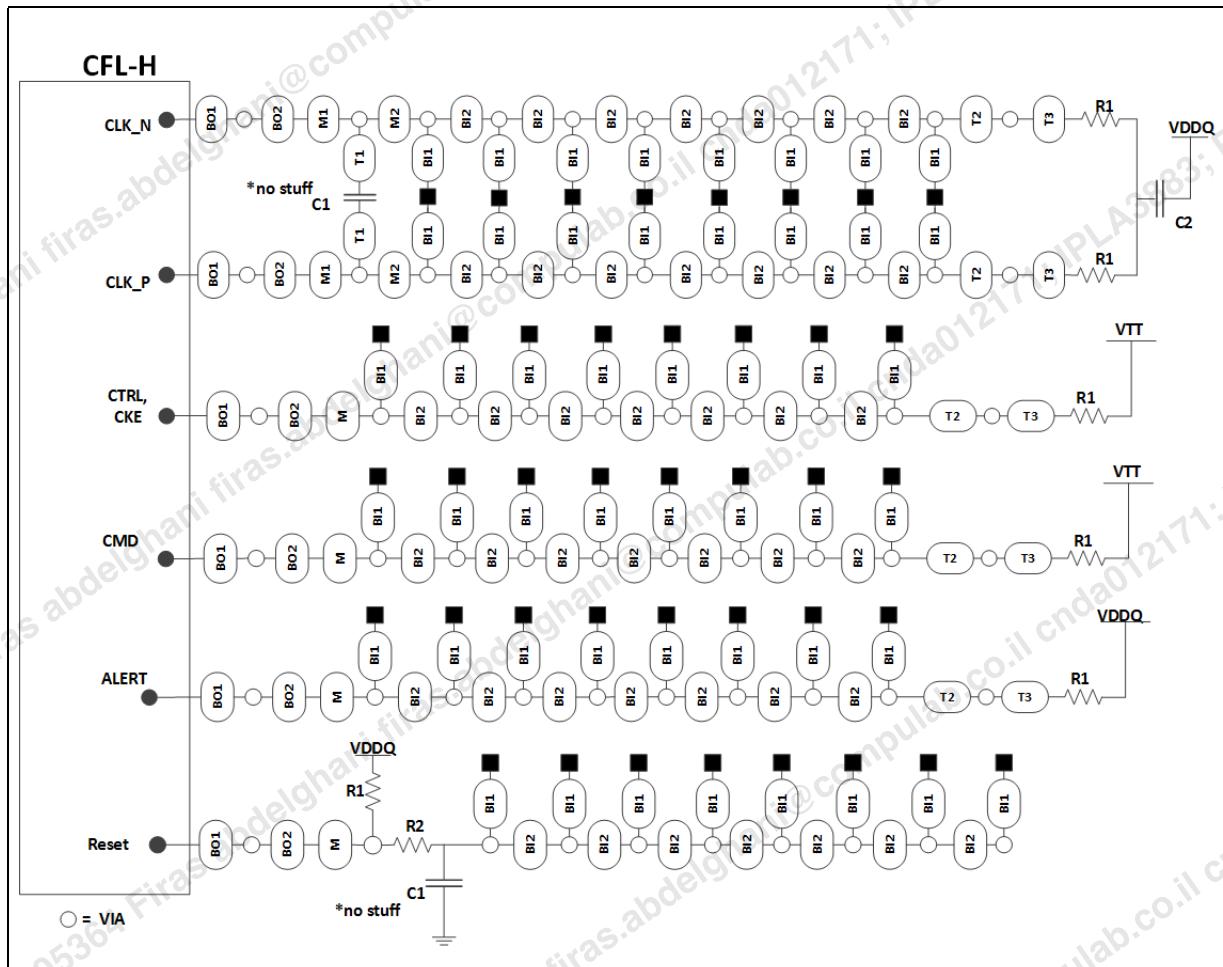


Figure 4-14. CFL-H DDR4 x8 Memory Down CLK/CKE/CMD/CTRL/ALERT/Reset Signals Topologies



Notes:

1. The alert signal must be routed in the opposite direction to the address/command bus. For example, the alert signal must first connect to the last device that the address/command bus is connected to.
2. DRAM_RST CAP should no stuffed

Figure 4-15. CFL-H DDR4 x8 Memory Down DQ/DQS/RCOMP Signals

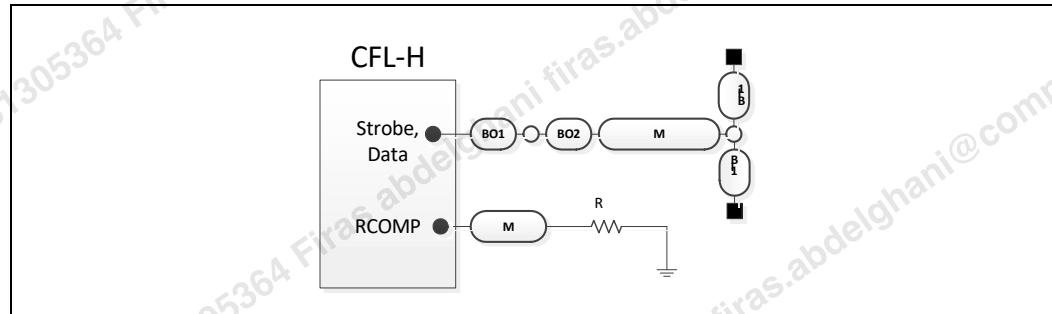



Table 4-14. CFL-H DDR4 x8 Memory Down Routing Guideline (Sheet 1 of 3)

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)				Max (mils) Length			$R (\Omega \pm 1\%)$ $C (\mu F)$	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group [1&2]	Byte [1&2]	Region	Breakout	Total		
CLK	BO1	MS	VSS	1	3				3.5	3.5	3.5		450	800	<div style="display: flex; justify-content: space-between;"> <div style="flex: 1;"> <div style="display: flex; justify-content: space-between;"> <div style="width: 33%;">[1st] 6000</div> <div style="width: 33%;">[Last] 10300</div> </div> <div style="display: flex; justify-content: space-between;"> <div style="width: 33%;">(R1) 36</div> <div style="width: 33%;">(C1-no stuff) 0.0033</div> <div style="width: 33%;">(C2) 0.01</div> </div> </div> </div>	1,2, 3, 7,8	
	BO2	SL	VSS	0	3.5				4	16	16		700				
	M1	SL	VSS	0	6/6.5	72		± 10	4.5	16	16						
	M2	SL	VSS	0	5/5.5				4.5/4	16	16		1000				
	BI1	SL	VSS	8	3				3.5	16	16		150				
	BI2	SL	VSS	0	4.5	85		± 10	4.5	16	16		700				
	T1	MS	VSS	1	3				3.5	16	16		200				
	T2	SL	VSS	0	4.5	85		± 10	4.5	16	16		300				
	T3	MS	VSS	1	3				3.5	16	16		50				
CTRL/ CKE	BO1	MS	VSS	1	3					3.5	3.5		450	800	<div style="display: flex; justify-content: space-between;"> <div style="flex: 1;"> <div style="display: flex; justify-content: space-between;"> <div style="width: 33%;">[1st] 6000</div> <div style="width: 33%;">[Last] 10300</div> </div> <div style="display: flex; justify-content: space-between;"> <div style="width: 33%;">36</div> <div style="width: 33%;">1,2, 3</div> <div style="width: 33%;"></div> </div> </div> </div>	1,2, 3	
	BO2	SL	VSS	0	3.5					4	16		700				
	M	SL	VSS	0	5.5/7		40	± 10		5/6	16						
	BI1	MS	VSS	8	3					3.5	16		150				
	BI2	SL	VSS	0	4.5		50	± 10		6.5	16		700				
	T2	SL	VSS	0	4.5		50	± 10		6.5	16		300				
	T3	MS	VSS	1	3					3.5	16		50				
CMD	BO1	MS	VSS	1	3					3.5	3.5		450	800	<div style="display: flex; justify-content: space-between;"> <div style="flex: 1;"> <div style="display: flex; justify-content: space-between;"> <div style="width: 33%;">[1st] 6000</div> <div style="width: 33%;">[Last] 10300</div> </div> <div style="display: flex; justify-content: space-between;"> <div style="width: 33%;">36</div> <div style="width: 33%;">1,2, 3</div> <div style="width: 33%;"></div> </div> </div> </div>	1,2, 3	
	BO2	SL	VSS	0	3.5					4	16		700				
	M	SL	VSS	0	5.5/7		40	± 10		4.5/ 5.5	16						
	BI1	MS	VSS	8	3					3.5	16		150				
	BI2	SL	VSS	0	4.5		50	± 10		6.5	16		700				
	T2	SL	VSS	0	4.5		50	± 10		6.5	16		300				
	T3	MS	VSS	1	3					3.5	16		50				

**Table 4-14. CFL-H DDR4 x8 Memory Down Routing Guideline (Sheet 2 of 3)**

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max (mils) Length			R ($\Omega \pm 1\%$)	C (μF)	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group[1&2]	Byte [1&2]	Region	Breakout	Total		
Alert	BO1	MS	VSS	1	3					3.5	3.5		450	800	[1st] 6000 [Last] 10300	(R1 connected to VDDQ) 50	1,2, 3
	BO2	SL	VSS	0	3.5					4	16		700				
	M	SL	VSS	0	5.5/7		40	± 10		4.5/ 5.5	16						
	BI1	MS	VSS	8	3					3.5	16		150				
	BI2	SL	VSS	0	4.5		50	± 10		6.5	16		700				
	T2	SL	VSS	0	4.5		50	± 10		6.5	16		300				
	T3	MS	VSS	1	3					3.5	16		50				
Strobe	BO1	MS	VSS	1	3				3.5		3.5	3.5	450	800	4500	(R1, R2, C1) 470, 0, 0.1	1,2, 4,5, 6,7, 9
	BO2	SL	VSS	0	3.5				4		16	25	700				
	M	SL	VSS	0	4/4.5	85	50	± 10	4.5		16	25					
	BI1	SL	VSS	1	3				3.5		16	25	150				
Data	BO1	MS	VSS	1	3					3.5	3.5	3.5	450	800	4500	(R1, R2, C1) 470, 0, 0.1	1,2, 4,5, 6,9
	BO2	SL	VSS	0	3.5					4		16	25	700			
	M	SL	VSS	0	4/4.5		50	± 10		4.5/ 5.5	16	25					
	BI1	SL	VSS	1	3					3.5	16	25	150				
Reset	BO1	MS	VSS	1	3						3.5		30	1000	10300	(R1) 470, (R2) 0, (C1) 0.1	3,8
	BO2	SL	VSS	0	3.5						20		1000				
	M	SL	VSS	1	4/4.5		50	± 10			20						
	BI1	MS	VSS	8	3						20						
	BI2	SL	VSS	0	4.5		50	± 10			20						
RCOMP [0]	M	MS/SL	VSS	4	12-15					13	13		500		500	121	
RCOMP [1]	M	MS/SL	VSS	4	12-15					13	13		500		500	121	10
RCOMP [2]	M	MS/SL	VSS	4	12-15					13	13		500		500	100	

**Table 4-14. CFL-H DDR4 x8 Memory Down Routing Guideline (Sheet 3 of 3)**

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)			Max (mils) Length			R ($\Omega \pm 1\%$) C (μF)	Notes
						Diff	Single Ended	Tolerance (%)	Diff	Group	Group to Group[1&2]	Byte [1&2]	Region	Breakout	Total	
Notes:	1. Avoid any parallel routing between two adjacent layers. When parallel routing can not be avoided in the CPU Break Out, it is recommended to offset the signals from two adjacent layers so no direct overlap occurs. If needed, the total parallel routing length in the CPU Break Out, which includes both overlapped and offset parallel routing, must be 300 mils or less. 2. Signals while routed on inner PCB layers must be ground referenced with solid ground floods on both sides. 3. Use individual termination resistors (R1) for each signal. Don't use Rpacks 4. For Option #1 (Single Rank) configuration there are only 8 DRAM Devices connected to each CMD Group Signal and only 1 DRAM Device connected to each Strobe/Data Group Signal. For these designs DRAM Devices [15:8] and their corresponding BI1 routing segments need to be removed for each CMD Group Signal and the second DRAM Device and corresponding BI routing segment needs to be removed for each Strobe/Data Group Signal. 5. The Strobe and Data Group Signals within the same byte must always route together on the same layers for their entire route 6. DQ Bit Swapping is allowed within the same byte, and Byte Swapping is allowed within the same channel 7. Clock (CLK and CLK#) and Strobe (DQS and DQS#) differential signal swapping within a pair is not allowed 8. Capacitor C1 is a defensive design and should be NO STUFF by default 9. DQ and DQS signals must route at the same layer and have same width 10. RCOMP[1] value for Mix SoDIMM and MD topology should be 75 Ohm															

Table 4-15. CFL-H DDR4 x8 Memory Down Length Matching Guidelines (Sheet 1 of 2)

Signal Group	Rule Details	Length Matching (mils)		Notes
		Min	Max	
CLK	BI1 (max - min)	0	50	2
	CK[X] - CK#[X]; where X = 0 or 1	-5	5	1,2
	CK/CK#[1:0] (max - min)	0	10	1,2
CTRL/CKE	BI1 (max - min)	0	0	2,4
	CTRL/CKE (max - min)	0	100	1,2
	CK/CK#[X] - CTRL/CKE; where X = 0 or 1	0	100	1,2,6
CMD	BI1 (max - min)	0	0	2,4
	CMD (max - min)	0	100	1,2,6
	CK/CK#[0] - CMD; where X = 0 or 1	-500	500	1,2
Strobe	BI1 (max - min)	0	0	2,5
	DQS[X] - DQS#[X], where X = 0 to 7	-5	5	1,2
	CK/CK#[X] - DQS/DQS#[Y], where X = 0 or 1 and Y = 0 to 7	-500	5500	1,2
Data	BI(max-min)	0	0	2,5
	DQ(Byte[X]) - DQS/DQS#[X], where X = 0 to 7	-20	20	1,2,3

**Table 4-15. CFL-H DDR4 x8 Memory Down Length Matching Guidelines (Sheet 2 of 2)****Notes:**

1. Length Matching = CPU Die to DRAM Ball of every DRAM Device (CLK = PKG+BO1+BO2+M1+M2+BI1+BI2, CTRL/CKE/CMD = PKG+BO1+BO2+M+BI1+BI2, Strobe/Data = PKG+BO1+BO2+M+BI1); where a conversion factor of 0.9 must be used on Micro-Strip Segments to convert Micro-Strip lengths to Strip-Line equivalent lengths
2. To help facilitate and check the Length and Matching relationships on a design please reference the Coffee Lake Platform System Memory Automated Trace Lengths Calculator (ATLC) #568458
3. Byte[0] = DQ[7:0], DQS/DQS#[0], Byte[1] = DQ[15:8], DQS/DQS#[1], Byte[2] = DQ[23:16], DQS/DQS#[2], Byte[3] = DQ[31:24], DQS/DQS#[3], Byte[4] = DQ[39:32], DQS/DQS#[4], Byte[5] = DQ[47:40], DQS/DQS#[5], Byte[6] = DQ[55:48], DQS/DQS#[6], Byte[7] = DQ[63:56], DQS/DQS#[7]
4. CMD/CTRL BI matching: this matching rule refer to all BI (Break-ins) sections that routed within each signal. For example: ADDR[0]/[1] BI1 should be equal in all DRAMs. ADDR[0] BI1 may be equal to ADDR[1] BI1.
5. DQ/DQS matching rules: DQ - BI should be matched within all bytes and not only within byte (max-min=0). DQ[63..0] BI section should be equal. DQS - BI should be matched within all bytes and not only within bytes (max-min=0). DQS[7..0][P/N] BI section should be equal. DQ and DQS BI does not need to be matched.
6. The delta between CLK signals to CMD/CTRL/CKE, between DRAMs should be kept < 20mils. For exp: |DRAM[x](CK[i]-Addr[j]) - DRAM[y](CK[i]-Addr[j])| < 20mils.

4.7**CFL-H DDR4 Mixed SODIMM and Memory Down x16 Daisy-Chain Topology****Table 4-16. System Memory Configuration Details Covered in this Section (Sheet 1 of 2)**

Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	SoDIMM Channel = One SODIMM MD Channel = x16 Memory Down (Four DRAM Devices)
Speed (MT/s)	2400/2666
Channels	2
System Memory Voltage	1.2V
Max Ranks Per Channel	SoDIMM Channel:2 Memory Down Channel:1
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	Mix with SDP:20GB,SODIMM 16GB+Memory Down 4 Devices of 1GB Mix with DDP:24GB,SODIMM 16GB+Memory Down 4 Devices of 2GB
SODIMM Raw-CARD Types	<u>2666:</u> RC-A(1Rx8),RC-E(2Rx8),RC-C(1Rx16) <u>2400:</u> RC-B(2Rx8)
Memory Down Types ^{1 2} (Pkg Ranks - Die Bits - Pkg bits)	96-Ball BGA <u>2666:SDP 1-16-16</u> <u>2400:DDP 1-8-16</u>
PCB Layers / Type ³	8L/T3
DRAM Device Placement	Top Motherboard Layer, Single Sided, Back-to-Back Placement Memory Down x16 Daisy-Chain Topology
Processor Memory Ball Map ⁴	Interleaved

**Table 4-16. System Memory Configuration Details Covered in this Section (Sheet 2 of 2)**

Parameter	Details
DRAM Device ODT Capability ⁵	Enabled
Total Max Length	SoDIMM Channel: Strobe/Data/CTRL/CLK/CKE/CMD=PKG+BO1+BO2+M+BI RCOMP=M Memory Down Channel: Strobe/Data/Reset = PKG+BO+M+BI CLK/CTRL/CKE/CMD= PKG+BO+M+BI1+BI2 RCOMP = M

Notes:

1. SDP: Single Die Package, DDP: Dual Die Package, QDP: Quad Die Package
2. No mixed vendor support within a channel and No mixed memory DRAM down type support (SDP, DDP, QDP) within a channel
3. Type 3 (T3)= PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias.
Type 4 (T4) (1-x-1+) = PCB with one build-up layer and two layers of Micro-vias.
Type 4 (T4) (2-x-2+) = PCB with two build-up layer and three layers of Micro-vias.
Type 4 (T4) (3-x-3+) = PCB with three build-up layer and four layers of Micro-vias.
See "Stack-Up and PCB Considerations" chapter for more details in this document.
4. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-by-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
5. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

For CFL-H DDR4 SO-DIMM Channel-Signals topology refer to [Figure 4-7, "CFL-H DDR4 SO-DIMM 2DPC Signals Topology"](#).

For CFL-H DDR4 SO-DIMM Channel - Signals Routing Guidelines refer to [Table 4-8, "CFL-H DDR4 SO-DIMM 1DPC Signal Routing Guidelines"](#)

For CFL-H DDR4 SO-DIMM Channel - Length Matching Guidelines refer to [Table 4-5, "CFL-H DDR4 ECC SO-DIMM Length and Matching Guidelines"](#),Please ignore ECC guidelines

For CFL-H DDR4 Memory Down x16 Channel-CLK/CTRL/CKE/CMD/Reset signals topology refer to [Figure 4-12, "CFL-H DDR4 1Rx16 Memory Down CLK/CTRL/CKE/CMD/Reset Signal Topology"](#)

For CFL-H DDR4 Memory Down x16 Channel-Strobe/Data/RCOMP signals topology refer to [Figure 4-11, "CFL-H DDR4 1Rx16 Memory Down Strobe/Data/RCOMP Signal Topologies"](#)

For CFL-H DDR4 Memory Down x16 Channel- signals routing topology refer to [Table 4-11, "CFL-H DDR4 1Rx16 Memory Down Routing Guideline"](#)

For CFL-H DDR4 Memory Down x16 Channel- Length Matching Guidelines refer to [Table 4-12, "CFL-H DDR4 1Rx16 Memory Down Length Matching Guidelines"](#)

Note:

Avoid any parallel routing for Memory down x16 Channel and SoDIMM Channel.



Note: For Mix Topology-SoDIMM with Memory down please use SoDIMM RCOMP [0],[1] and [2] value

4.8 CFL-H DDR4 Mixed SODIMM and Memory Down x8 Daisy-Chain Topology

Table 4-17. System Memory Configuration Details Covered in this Section

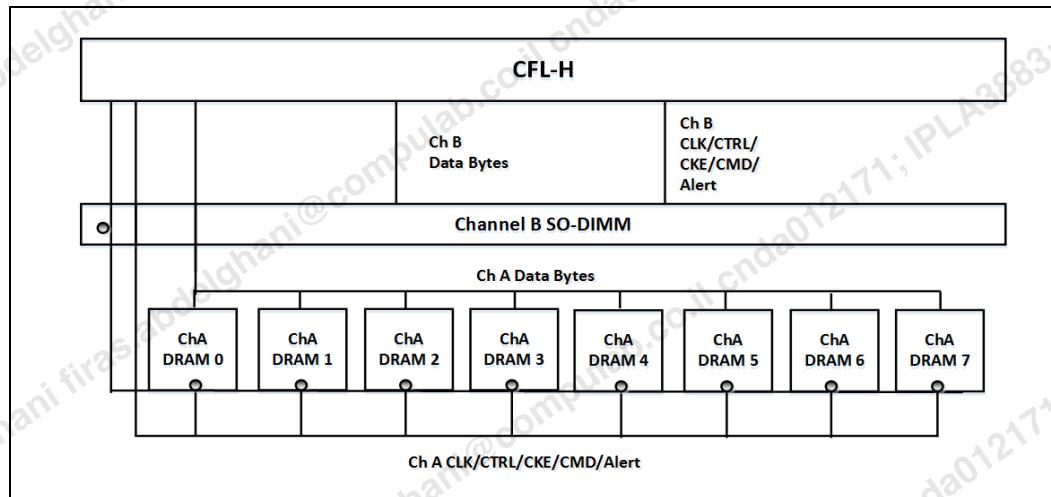
Parameter	Details
Processor	CFL-H
Memory Type	DDR4
Configuration	SoDIMM Channel = One SODIMM MD Channel = x8 Memory Down (Eight DRAM Devices)
Speed (MT/s)	2400/2666
Channels	2
System Memory Voltage	1.2V
Max Ranks Per Channel	SoDIMM Channel:2 Memory Down Channel:1
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	24GB,SODIMM 16GB+Memory Down 8 Devices of 1GB
SODIMM Raw-CARD Types	2666:RC-A(1Rx8),RC-E(2Rx8),RC-C(1Rx16) 2400:RC-B(2Rx8)
Memory Down Types ^{1 2} (Pkg Ranks - Die Bits - Pkg bits)	78-Ball BGA SDP 1-8-8
PCB Layers / Type ³	8L/T3
DRAM Device Placement	Top Motherboard Layer, Single Sided, Back-to-Back Placement Memory Down x8 Daisy-Chain Topology
Processor Memory Ball Map ⁴	Interleaved
DRAM Device ODT Capability ⁵	Enabled
Total Max Length	SoDIMM Channel: Strobe/Data/CTRL/CLK/CKE/CMD=PKG+BO1+BO2+M+BI RCOMP=M Memory Down Channel: Strobe/Data = PKG+BO1+BO2+M+BI1 Reset = PKG+BO1+BO2+M+BI1+BI2 CLK = PKG+BO1+BO2+M1+M2+BI1+BI2 CTRL/CKE/CMD= PKG+BO1+BO2+M+BI1+BI2 RCOMP = M

Notes:

1. SDP: Single Die Package, DDP: Dual Die Package, QDP: Quad Die Package
2. No mixed vendor support within a channel and No mixed memory DRAM down type support (SDP, DDP, QDP) within a channel.
3. Type 3 (T3)= PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias.
Type 4 (T4) (1-x-1+) = PCB with one build-up layer and two layers of Micro-vias.
Type 4 (T4) (2-x-2+) = PCB with two build-up layer and three layers of Micro-vias.
Type 4 (T4) (3-x-3+) = PCB with three build-up layer and four layers of Micro-vias.
See "Stack-Up and PCB Considerations" chapter for more details in this document.
4. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-by-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.

5. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to [Table 4-21, "ODT Signals Connectivity Table"](#).

Figure 4-16. CFL-H DDR4 x8 Memory Down Placement and Block Diagram



For CFL-H DDR4 SO-DIMM Channel-Signals topology refer to [Figure 4-7, "CFL-H DDR4 SO-DIMM 2DPC Signals Topology"](#).

For CFL-H DDR4 SO-DIMM Channel - Signals Routing Guidelines refer to [Table 4-8, "CFL-H DDR4 SO-DIMM 1DPC Signal Routing Guidelines"](#)

For CFL-H DDR4 SO-DIMM Channel - Length Matching Guidelines refer to [Table 4-5, "CFL-H DDR4 ECC SO-DIMM Length and Matching Guidelines"](#), Please ignore ECC guidelines

For CFL-H DDR4 Memory Down x8 Channel-CLK/CTRL/CKE/CMD/Reset signals topology refer to [Figure 4-14, "CFL-H DDR4 x8 Memory Down CLK/CKE/CMD/CTRL/Reset Signals Topologies"](#)

For CFL-H DDR4 Memory Down x8 Channel-Strobe/Data/RCOMP signals topology refer to [Figure 4-15, "CFL-H DDR4 x8 Memory Down DQ/DQS/RCOMP Signals"](#)

For CFL-H DDR4 Memory Down x8 Channel- signals routing topology refer to [Table 4-14, "CFL-H DDR4 x8 Memory Down Routing Guideline"](#)

For CFL-H DDR4 Memory Down x8 Channel- Length Matching Guidelines refer to [Table 4-15, "CFL-H DDR4 x8 Memory Down Length Matching Guidelines"](#)

Note: Avoid any parallel routing for Memory down x8 Channel and SoDIMM Channel.

Note: For Mix Topology-SoDIMM with Memory down please use SoDIMM RCOMP [0],[1] and [2] value



4.9 CFL-H LPDDR3 x32 Memory Down

Table 4-18. System Memory Configuration Details Covered in this Section

Parameter	Details
Processor	CFL-H62
Memory Type	LPDDR3
Configuration	Channel A = x32 Memory Down (Two DRAM Devices) Channel B = x32 Memory Down (Two DRAM Devices)
Speed (MT/s)	2133
Channels	1 and 2
System Memory Voltage	1.2V
Max Ranks Per Channel	2
DRAM Die Density (Gb)	4 and 8
Max Capacity (GB)	16
Memory Down Types ^{1 2} (Pkg Ranks - Die Bits - Pkg bits)	178-Ball BGA SDP 1-32-32, DDP 2-32-32, and QDP 2-16-32
PCB Layers / Type ³	10L/T4 (3-x-3+)
DRAM Device Placement	Top Motherboard Layer, Single Sided, Side by Side Placement
Processor Memory Ball Map ⁴	Non-Interleaved
DRAM Device ODT Capability ⁵	Disabled
Total Max Length	Strobe/Data/CNTL = PKG+BO+M+BI CLK/CKE/CMD = PKG+BO+M RCOMP = M

Notes:

1. SDP: Single Die Package, DDP: Dual Die Package, QDP: Quad Die Package
2. No mixed vendor support within a channel or channel to channel and No mixed memory DRAM down type support (SDP, DDP, QDP) within a channel or channel to channel
3. Type 3 (T3)= PCB with zero build-up layers using Plated Through-hole (PTH) Vias with no Micro-vias.
Type 4 (T4) (1-x-1+) = PCB with one build-up layer and two layers of Micro-vias.
Type 4 (T4) (2-x-2+) = PCB with two build-up layer and three layers of Micro-vias.
Type 4 (T4) (3-x-3+) = PCB with three build-up layer and four layers of Micro-vias.
See "Stack-Up and PCB Considerations" chapter for more details in this document.
4. Non-Interleave = The processor is optimized for a side-by-side ball map and placement of the DRAM memory down devices or DIMM Side-by-Side (inline) placement. Each memory channel's signals are grouped together on one side of the processor packages.
Interleave = the processor is optimized for a back-to-back ball map and placement of the DIMMs. Each memory channel's signals are grouped together on front or back side of the processor packages.
5. The DRAM Device ODT Capability can be enabled or disabled for reads and writes depending on the system memory interface margins. Enabling the DRAM device ODT increases the memory interface power and improves signal integrity/margins while disabling the DRAM device ODT decreases the memory interface power but degrades signal integrity/margins. For ODT implementation recommendation for this topology refer to Table 4-21, "ODT Signals Connectivity Table".

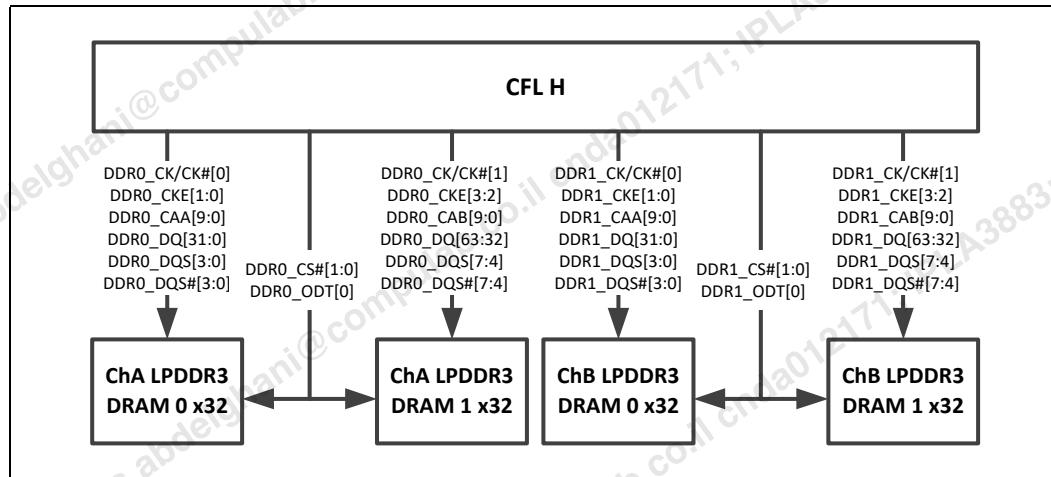
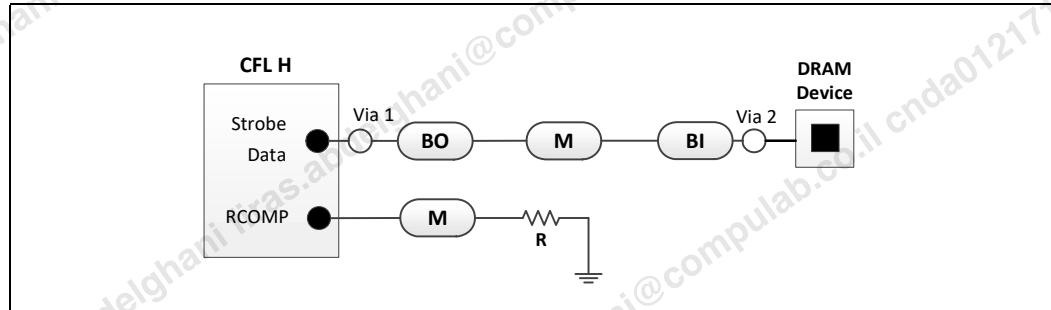
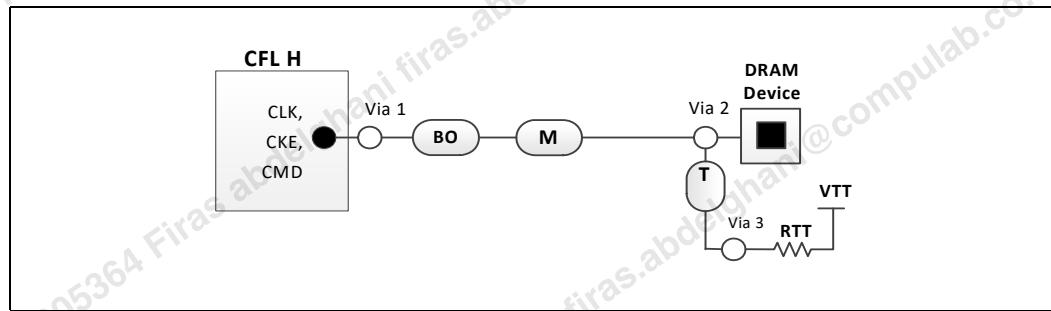
Figure 4-17. CFL-H LPDDR3 x32 Memory Down Placement and Block Diagram

Figure 4-18. CFL-H LPDDR3 x32 Memory Down Strobe/Data/RCOMP Signal Topologies

Figure 4-19. CFL-H LPDDR3 x32 Memory Down CLK/CKE/CMD Signal Topologies




Figure 4-20. CFL-H LPDDR3 x32 Memory Down CTRL Signal Topologies

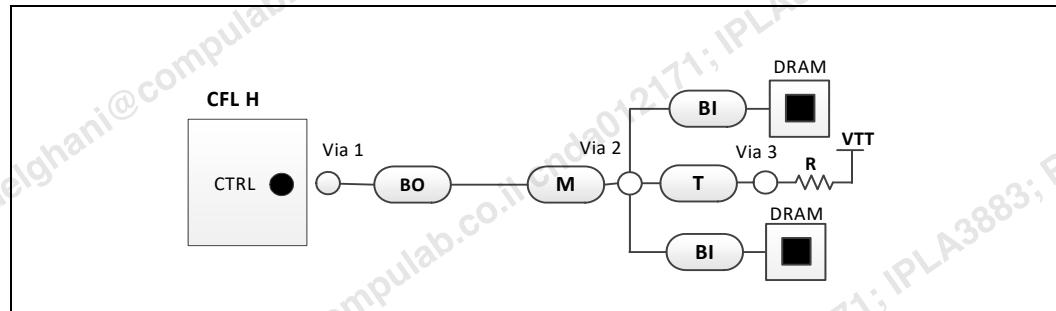


Table 4-19. CFL-H LPDDR3 x32 Memory Down Routing Guidelines (Sheet 1 of 2)

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)				Max (mils) Length			Notes
						Diff	Single Ended	Tolerance	Diff	Group	Group to Group[1&2]	Byte [1&2]	Region	Total	R ($\Omega \pm 1\%$)	
CLK	BO	SL	VSS	1	3				3	6	6		300	4000	38	1,2,3, 4,7
	M	SL	VSS	1	3	70		± 10	4	12	12					
	T	SL/MS	VSS	1	3				3	12	12		400			
CTRL	BO	SL	VSS	1	3						4.5	6	300	4000	80	1,2,3, 4
	M	SL	VSS	0	3		40	± 10			8	12				
	BI	SL	VSS	1	3						8.5	12	400			
	T	MS	VSS	1	3						10	12	500			
CKE	BO	SL	VSS	1	3						4.5	6	300	4000	80	1,2,3, 4
	M	SL	VSS	1	3		40	± 10			8	12				
	T	MS	VSS	1	3						10	12	500			
CMD	BO	SL	VSS	1	3						4.5	6	300	4000	68	1,2,3, 4
	M	SL	VSS	1	3		40	± 10			8	12				
	T	SL/MS	VSS	1	3						10	12	500			
Strobe	BO	SL	VSS	1	3				3		6	6	300	3000	1,2,3, 5,6,7, 8	
	M	SL	VSS	0	3	70		± 10	3.5		25	16				
	BI	SL	VSS	1	3				3.5		12	10	300			
Data	BO	SL	VSS	1	3						4.5	6	300	3000	1,2,3, 5,6,8	
	M	SL	VSS	0	3		40	± 10			9	25	16			
	BI	SL	VSS	1	3						4.5	12	300			
RCOMP[0]	M	SL/MS	VSS	5	12-15						20	25	500	500	200	
RCOMP[1]	M	SL/MS	VSS	5	12-15						20	25	500	500	121	

**Table 4-19. CFL-H LPDDR3 x32 Memory Down Routing Guidelines (Sheet 2 of 2)**

Signal Group	Region	Layer Route	Reference	Via Count	Trace Width (mils)	Target Impedance (Ω)			Min Trace Spacing (mils)				Max (mils) Length		R ($\Omega \pm 1\%$)	Notes
						Diff	Single Ended	Tolerance	Diff	Group	Group to Group[1&2]	Byte [1&2]	Region	Total		
RCOMP[2]	M	SL/MS	VSS	5	12-15				20	25		500	500	162		

Notes:

1. Avoid any parallel routing between two adjacent layers.
2. With Type 4 PCB there must not be any microstrip routing for pin escapes at the CPU or DRAM sides (via-in-pad technology)
3. Signals while routed on inner PCB layers must be ground referenced with solid ground floods on both sides.
4. Use individual termination resistors (RTT) for each signal. Don't use R-packs
5. Strobe and Data Group Signals within the same byte must route together.
6. DQ Bit Swapping is allowed within the same byte, and Byte Swapping is allowed within the same channel
7. Clock (CLK and CLK#) and Strobe (DQS and DQS#) differential signal swapping within a pair is not allowed. Also differential clock pair to clock pair swapping within a channel is not allowed
8. DQ and DQS signals must route at the same layer and have same width.

Table 4-20. CFL-H LPDDR3 x32 Memory Down Length Matching Guidelines

Signal Group	Rule Details	Min	Max	Notes
CLK	CK[X] - CK#[X]; where X = 0 or 1	-5	5	1,2
CTRL/CKE	BI (max - min)	0	24	1
	CTRL/CKE (max - min)	0	100	1,2
	CK/CK#[1:0] - CTRL/CKE	-250	250	1,2
CMD	CMD (max - min)	0	100	1,2,3
	CK/CK#[1:0] - CMD	-500	500	1,2
Strobe	DQS[X] - DQS#[X]; where X = 0 to 7	-5	5	1,2
	CK/CK#[1:0] - DQS/DQS#[X]; where X = 0 to 7	-1500	2500	1,2
Data	Byte[X](DQmax - DQmin), X = 0 to 7	0	250	1,2
	DQ(Byte[X]) - DQS/DQS#[X], where X = 0 to 7	-400	100	1,2,4

Notes:

1. Length Matching = CPU Die to DRAM Ball (PKG + BO + M, PKG + BO + M + BI); where a conversion factor of 0.9 must be used on Micro-Strip Segments to convert Micro-Strip lengths to Strip-Line equivalent lengths
2. To help facilitate and check the Length and Matching relationships on a design please reference the [Coffee Lake Platform System Memory Automated Trace Lengths Calculator \(ATLC\) #568458](#)
3. The CFL H documented Clock to CTRL/CKE Length Matching rule is considered the "Absolute Minimum Requirement." If possible it is strongly recommended to length match the CLK and CTRL/CKE signals with the following relationship for optimal timing margins. CK/CK#[0] - CTRL/CKE: Min = 0 mils, Max = 200 mils
4. Byte[0] = DQ[7:0], DQS/DQS#[0], Byte[1] = DQ[15:8], DQS/DQS#[1], Byte[2] = DQ[23:16], DQS/DQS#[2], Byte[3] = DQ[31:24], DQS/DQS#[3], Byte[4] = DQ[39:32], DQS/DQS#[4], Byte[5] = DQ[47:40], DQS/DQS#[5], Byte[6] = DQ[55:48], DQS/DQS#[6], Byte[7] = DQ[63:56], DQS/DQS#[7]. Two Byte Clusters are grouped as Bytes[1:2], Bytes[3:2], Bytes[5:4] and Bytes[7:6]



4.10 CFL-H System Memory ODT Signal Connectivity Details

Table 4-21. ODT Signals Connectivity Table

Processor	Memory type	Side	Signal	Rule	Notes
CFL-H	DDR4 Memory Down	Processor	DDR0_ODT[3:0] DDR1_ODT[3:0]	Processor's ODT[1:0] balls connected to DRAMs' ODT balls. Processor's ODT[3:2] balls not connected.	
		DRAMs	ODT[1:0] for two Ranks per channel		
	DDR4 SO-DIMM 1DPC	Processor	DDR0_ODT[3:0] DDR1_ODT[3:0]	Processor's ODT[1:0] balls connected to DRAMs' ODT balls. Processor's ODT[3:2] balls not connected.	1
		DRAMs	ODT[1:0]		
	DDR4 SO-DIMM 2DPC	Processor	DDR0_ODT[3:0] DDR1_ODT[3:0]	Processor's ODT[3:0] balls connected to DRAMs' ODT balls.	1
		DRAMs	ODT[3:0]		
	LPDDR3 Memory Down	Processor	DDR0_ODT[3:0] DDR1_ODT[3:0]	Processor's ODT[0] balls connected to DRAMs' ODT balls. T-topology connection. Processor's ODT[3:1] balls not connected.	1
		DRAMs	ODT[0]		

Notes:

- For additional ODT signal connection details reference the Customer Reference Board (CRB) schematics and board files (RVP11 -CFL -H DDR4 SODIMM, RVP16 - CFL-H LPDDR3)

4.11 Memory Data Mask (DM) Signals Connectivity Details

Table 4-22. DIMMs/DRAMs DM Signals Connectivity Table

Memory type	DM signals	Connect to
LPDDR3 Memory Down	DRAMs DM[7:0]	Tied to GND
DDR4 Memory Down	DRAMs DM[7:0]	Tied to VDDQ
DDR4 DIMMs	DIMMs DM[8:0]	Tied to VDDQ

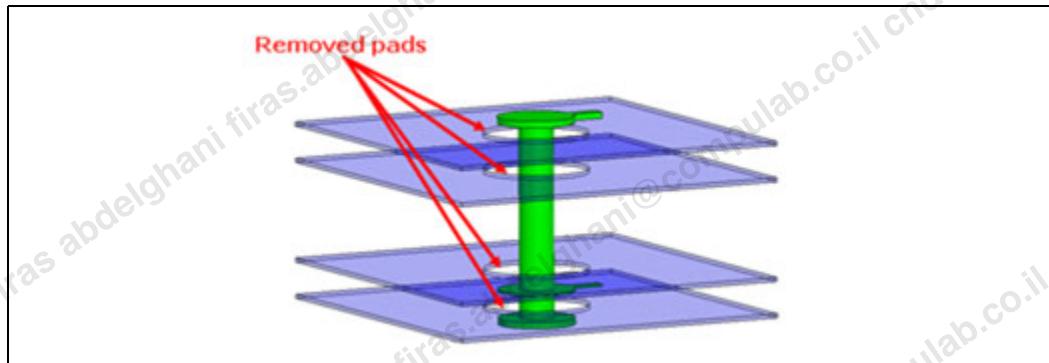
4.12 CFL H System Memory Via Placement and Pad Optimization Guidelines

4.12.1 Via Placement at CPU Side

Ensure reference plane stitching vias are placed in close proximity of every system memory signal transition via at the CPU side

- Follow the Customer Reference Board (CRB) via placement at CPU side as much as possible for all Signal Groups.
- At least one ground stitching via must be placed from every signal transition via when ever they change signal layers.
- When a signal transitions to a layer in between two reference planes, make sure the stitching via connects to the plane closest to the signal layer.
- When a signal transitions to another routing layer, but the referencing plane still kept the same, no stitching via is required.
- GND/PWR vias should be placed between signals from different signal groups and channels.
- Where possible Data and Strobe vias from different byte lanes should be separated by GND vias.
- For Type 4 (2-x-2+) memory down PCB designs use Stacked Micro Vias from layer 1 to layer 2 or 4 under the processor rather than using Staggered Micro Vias to help minimize voiding on layers 1,3 and 5 reference planes.
- Remove via pads from layers that are not connected to traces ([Figure 4-21](#)).

Figure 4-21. Remove PADs from Layers that Do Not Connect to Trace



4.12.2

Via Placement at SO-DIMM and DRAM Device Side

Ensure reference plane transition vias are placed in close proximity of every system memory signal transition via at the SO-DIMM or DRAM Device side.

- Follow the Customer Reference Board (CRB) via placement at SO-DIMM or Memory DRAM Down side as much as possible for all Signal Groups.
- At least one ground stitching via must be placed from every signal transition via when ever they change signal layers.
- For Type 4 (2-x-2+) memory down PCB designs use Stacked Micro Vias from layer 1 to layer 2 or 4 under the DRAM Devices rather than using Staggered Micro Vias to help minimize voiding on layers 1,3 and 5 reference planes.
- Follow the via spacing guidelines covered in [Table 4-23](#)
- Remove via pads from layers that are not connected to traces ([Figure 4-21](#)).

**Table 4-23. CFL H Guidelines for Vias Separation**

CPU	Memory Type	Signal Group	Rule	Pitch (mils)	Notes
CFL H	SO-DIMM	DQ/DQS/DQS# to GND	>= 1 GND via	30	1
		CLK/CTRL/CKE/CMD to GND	>= 1 GND via	30	1
		1 DIMM Per Channel	Pitch between DQ vias from different byte lanes >	60	
			Pitch between CMD to CTRL vias >	60	
	Memory Down	DQ/DQS/DQS#	>= 1 GND via	70	1
		CLK/CTRL/CKE/CMD	>= 1 PWR/GND via	70	1
		DQ to DQ from different byte lanes	Pitch between DQ vias from different byte lanes >	37	2

Notes:

1. Due to space constrains, it is acceptable to have one GND via for every two transition signal vias.
2. This via-to-via separation is between Micro Vias, not PTH Vias.

4.13 CFL H System Memory Reference Voltage (VREF) Guidelines

System memory reference voltages, VREF_DQ_A, VREF_DQ_B, VREF_CA must meet the following guidelines:

- Follow the Customer Reference Board (CRB) board file and schematic implementation as closely as possible.
- The figures at this section show the VREF implementation block diagrams for all supported platform configurations.
- Place the VREF voltage dividers as close as possible to the SO-DIMMs or memory down DRAM devices.
- All VREF traces should be at least 20 mils wide with 20 mils spacing to other signals/planes. Short violations are acceptable if required due to tight routing constraints.

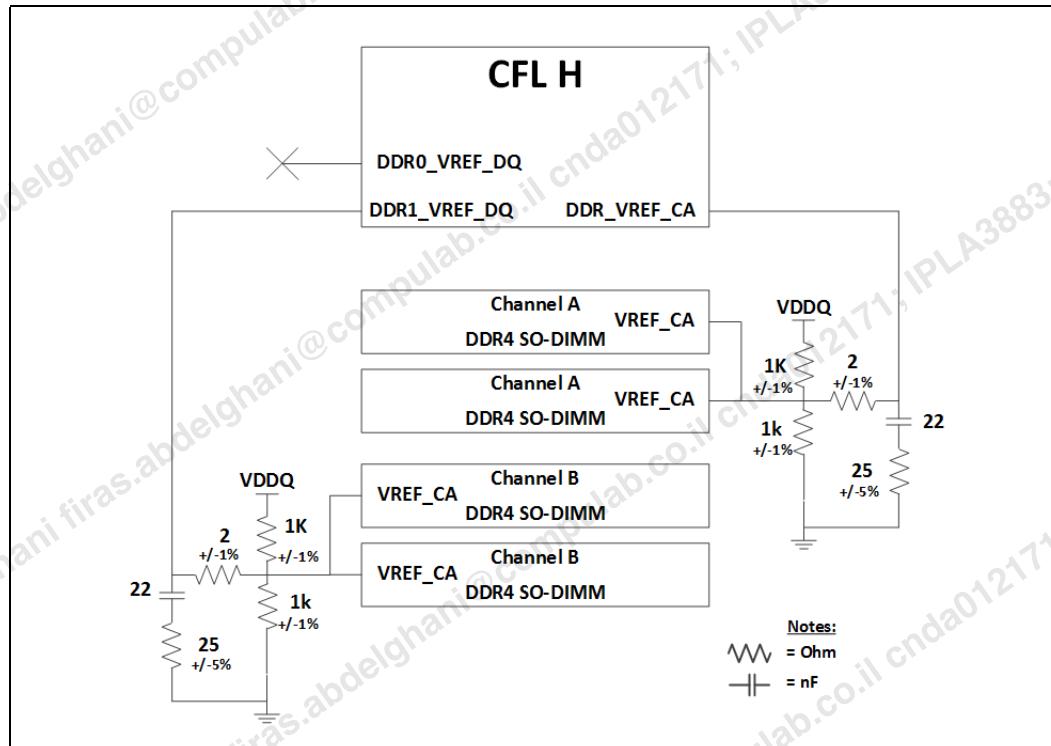
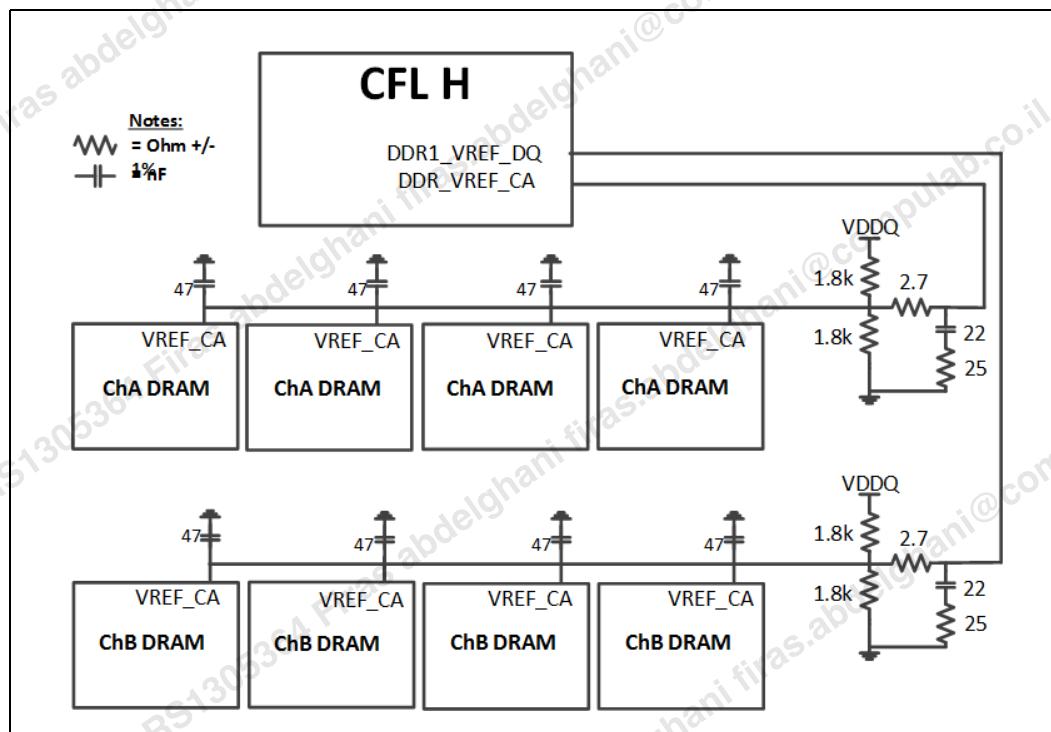
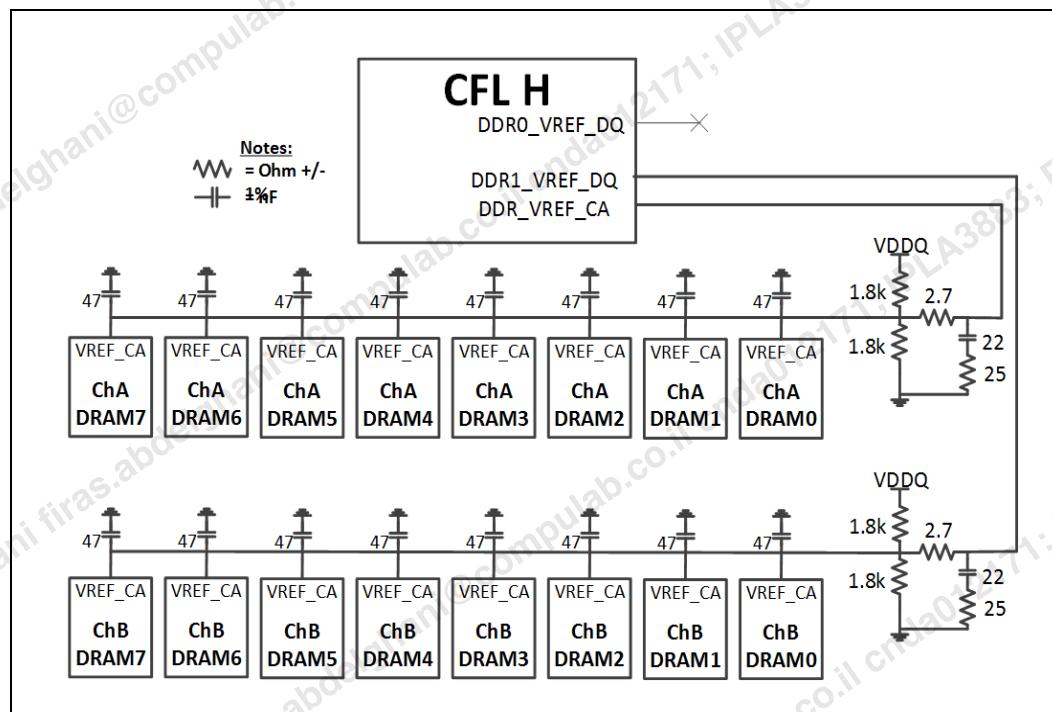
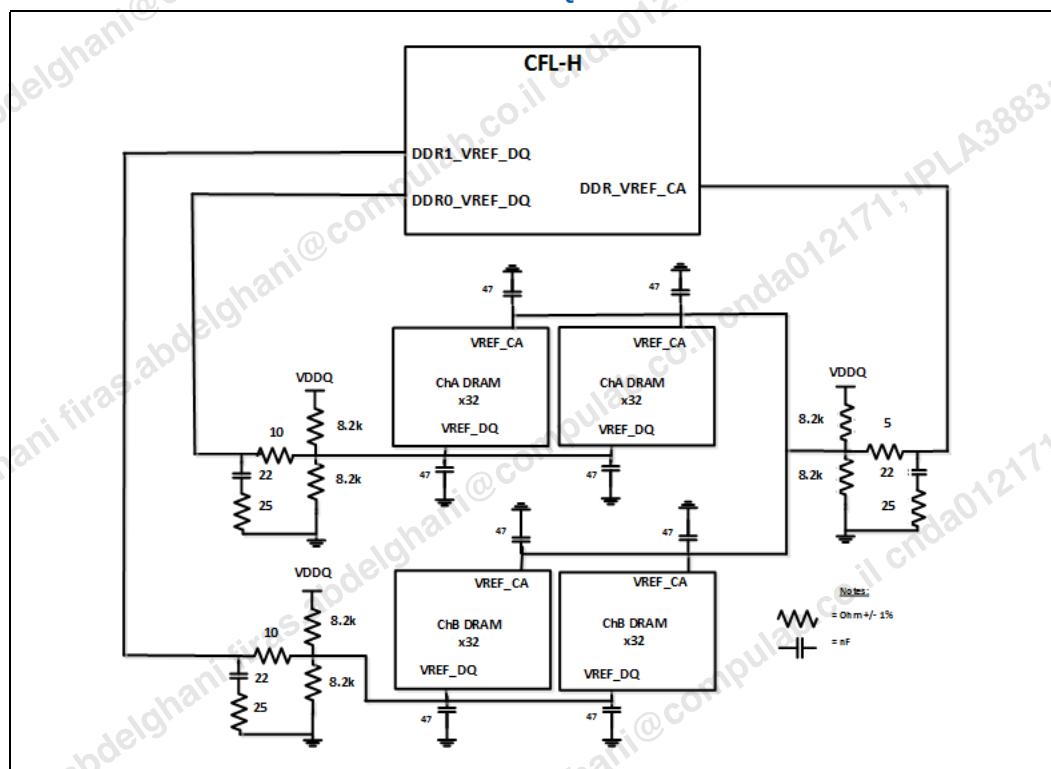
Figure 4-22. CFL-H DDR4 SO-DIMM V_{REF-CA} Overview

Figure 4-23. CFL-H DDR4 x16 Memory Down V_{REF-CA} Overview


Figure 4-24. CFL-H DDR4 x8 Memory Down V_{REF-CA} Overview

Note:

For 2Rx8 each DRAM should have its own cap (47nF) – 16 caps per channel. In overall 32 caps.

Figure 4-25. CFL-H LPDDR3 x32 Memory Down V_{REF-DQ} and V_{REF-CA} Overview



4.14 CFL-H DDR Power Delivery - Memory side

The guidelines here are to support a single sided component assembly.

The expectation is that the decoupling caps will be placed as close as possible to the DRAM devices or SODIMMs to minimize the loop inductance of the caps. A placement of farther than 5mm is not recommended.

The decoupling capacitor to DRAM/SODIMM inductance loop is better with single sided assembly, if the power and ground planes are strongly coupled, and cap placement and connection by common power integrity practices.

Dual sided designs may prove to be a superior solution for certain board technologies, thickness of the stackup and placement location of the caps under the memory devices. This document does not cover the dual sided assembly guidelines.



4.14.1 CFL-H DDR4 SODIMM Decoupling

Table 4-24. DDR4 SODIMM Power Plane Decoupling

Memory Configuration	Power Domain	Decoupling Location	Qty x μ F (size)	Note
DDR4 2 Channels SODIMM 1DPC	VDDQ	4 near each side of the DIMM connector close to VDD pins	16x 10 μ F (0603)	
		4 near each side of the DIMM connector close to VDD pins	16x 1 μ F (0402)	
		1 placeholder	1x 330 μ F (7343)	
	VTT	Placed on VTT plane close to DIMM, 1 cap stuffed, 1 placeholder	2x 10 μ F (0603)	
		Placed on VTT plane close to DIMM	4x 1 μ F (0402)	
	VPP	DIMM Pin side, 1 per DIMM	2x 10 μ F (0603)	
		DIMM Pin side, 1 per DIMM	2x 1 μ F (0402)	
	VDDSPD	Place close to DIMM	2x 0.1 μ F (0402)	
		Place close to DIMM	2x 2.2 μ F (0402)	
DDR4 2 Channels SODIMM 2DPC	VDDQ	4 near each side of the DIMM connector close to VDD pins	32 x 10 μ F (0603)	
		4 near each side of the DIMM connector close to VDD pins	32 x 1 μ F (0402)	
		Placeholder	2x 330 μ F (7343)	
	VTT	Placed on VTT plane close to DIMM, 1 cap stuffed, 1 placeholder	4x 10 μ F (0603)	
		Placed on VTT plane close to DIMM	8x 1 μ F (0402)	
	VPP	DIMM Pin side, 1 per DIMM	4x 10 μ F (0603)	
		DIMM Pin side, 1 per DIMM	4 x 1 μ F (0402)	
	VDDSPD	Place close to DIMM	4x 0.1 μ F (0402)	
		Place close to DIMM	4x 2.2 μ F (0603)	

Notes:

- Total quantity is referring to 2 channels.



4.14.2 CFL-H DDR4 Memory Down Decoupling

This recommendation assumes a 2Ch memory down implementation.

Table 4-25. DDR4 Memory Down Power Plane Decoupling

Memory Configuration	Power Domain	Decoupling Location	Qty x μ F (size)	Note	
DDR4 Memory Down x16 - 4 Devices per Channel	VDDQ/VDD (shorted)	4 per dram, as close as possible	32x 1 μ F (0402) (All stuffed)		
		Distributed evenly across domain, close by Drams	10x 10 μ F (0603) (All stuffed)		
	VPP	2 per dram, as close as possible	16x 1 μ F (0402)		
		Distributed evenly across domain, close by Drams	5x 10 μ F (0603)		
	VTT	Distributed along termination resistors	16x 1 μ F (0402)		
		Distributed evenly across domain	4x 10 μ F (0603)		
DDR4 Memory Down x8- 8 Devices per Channel	VDDQ/VDD (shorted)	4 as near each x8 DRAM device as possible	64x 1 μ F (0402) (min of 48 stuffed)		
		Distributed around the DRAM devices	20x 10 μ F (0603) (min of 12 stuffed)		
	VPP	2 as near each x8 DRAM device as possible	32x 1 μ F (0402)		
		Distributed around the DRAM devices	10x 10 μ F (0603)		
	VTT	Distributed along termination resistors	32x 1 μ F (0402)		
		Distributed evenly across domain	8x 10 μ F (0603)		
DDR4 Memory Down x8- 16 Devices per Channel	VDDQ/VDD (shorted)	4 as near each x8 DRAM device as possible	128x 1 μ F (0402) (min of 96 stuffed)		
		Distributed around the DRAM devices	40x 10 μ F (0603) (min of 24 stuffed)		
	VPP	2 as near each x8 DRAM device as possible	64x 1 μ F (0402)		
		Distributed around the DRAM devices	20x 10 μ F (0603)		
	VTT	Distributed along termination resistors	64x 1 μ F (0402)		
		Distributed evenly across domain	16x 10 μ F (0603)		
Notes:					
1. Total quantity is referring to 2 channels.					

4.14.3 CFL-H LPDDR3 x32 Memory Down Decoupling

This decoupling solution assumes a memory down implementation of four x32bit DRAM devices.

The isolation requirement of the DRAM power domains reduces cap sharing resulting in higher cap counts than DDR3L memory down. The power domains are VDD1, VDD2, VDDCA, and VDDQ.

Figure 4-26. Decoupling Connections at the LPDDR3 Device

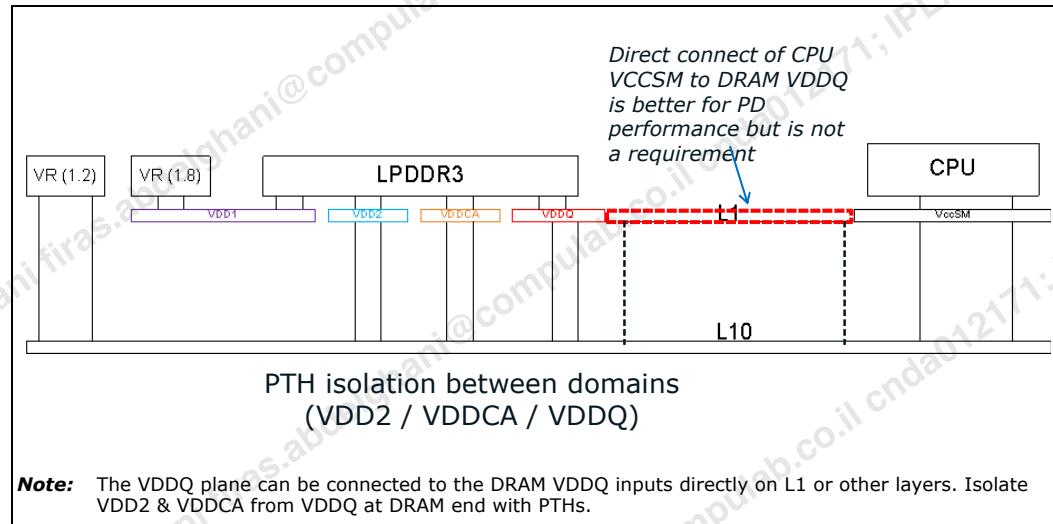




Table 4-26. LPDDR3 x32 Power Plane Decoupling (Sheet 1 of 2)

Memory Configuration	Power Domain	Decoupling Location	Qty x μ F (size)	Note
Config 1 LPDDR3 Memory Down x32 - 2 Devices per Channel	VDDQ	Distributed evenly across domain, close by DRAMs, VDDQ red circles Figure 4-28	5x 10 μ F (0603)	2
		4 caps per DRAM, Figure 4-27 VDDQ red circles	16x 1 μ F (0402)	2
	VDDCA	2 caps per DRAM, Figure 4-27 VDDCA yellow circles	8x 1 μ F (0402)	2
		Distributed evenly across domain, close by DRAMs, VDDCA yellow circles Figure 4-28	2x 10 μ F (0603)	2
	VDD2	Distributed evenly across domain, close by DRAMs, VDD2 blue circles Figure 4-28	5x 10 μ F (0603)	2
		3 caps per DRAM, Figure 4-27 VDD2 blue circles	12x 1 μ F (0402)	2
	VDD1	2 caps per DRAM, Figure 4-27 VDD1 pink circles	8x 1 μ F (0402)	2
		Distributed evenly across domain, close by DRAMs, VDD2 blue circles Figure 4-28	5x 10 μ F (0603)	2
	VTT	Distributed along termination resistors.Caps shown in blue Figure 4-29	8x 1 μ F (0402)	
		Distributed evenly across domain, close by terminations	4x 10 μ F (0603)	
Config 2 LPDDR3 Memory Down x32 - 2 Devices per Channel	VDDQ	Distributed evenly across domain, close by DRAMs, VDDQ red circles Figure 4-28	5x 10 μ F (0603)	2
		2 caps per DRAM, Figure 4-27 VDDQ red circles	8x 1 μ F (0402)	2
	VDDCA	2 caps per DRAM, Figure 4-27 VDDCA yellow circles	8x 1 μ F (0402)	2
		Distributed evenly across domain, close by DRAMs, VDDCA yellow circles Figure 4-28	2x 10 μ F (0603)	2
	VDD2	1 cap for northern VDD2 pins on each DRAM (total 4), 3 caps between DRAMs	5x 10 μ F (0603)	2
		3 caps per DRAM, Figure 4-27 VDD2 blue circles	7x 1 μ F (0402)	2
	VDD1	1 caps per DRAM, Figure 4-27 VDD1 pink circles	4x 1 μ F (0402)	2
		Distributed evenly across domain, close by DRAMs, VDD2 blue circles Figure 4-28	5x 10 μ F (0603)	2
	VTT	Distributed along termination resistors.Caps shown in blue Figure 4-29	4x 1 μ F (0402)	
		Distributed along termination resistors.	4x 10 μ F (0603)	

Table 4-26. LPDDR3 x32 Power Plane Decoupling (Sheet 2 of 2)

Memory Configuration	Power Domain	Decoupling Location	Qty x μ F (size)	Note
Notes:				
1. Total quantity is referring to 2 channels. 2. Distributed among the 4 LPDDR3 Devices				

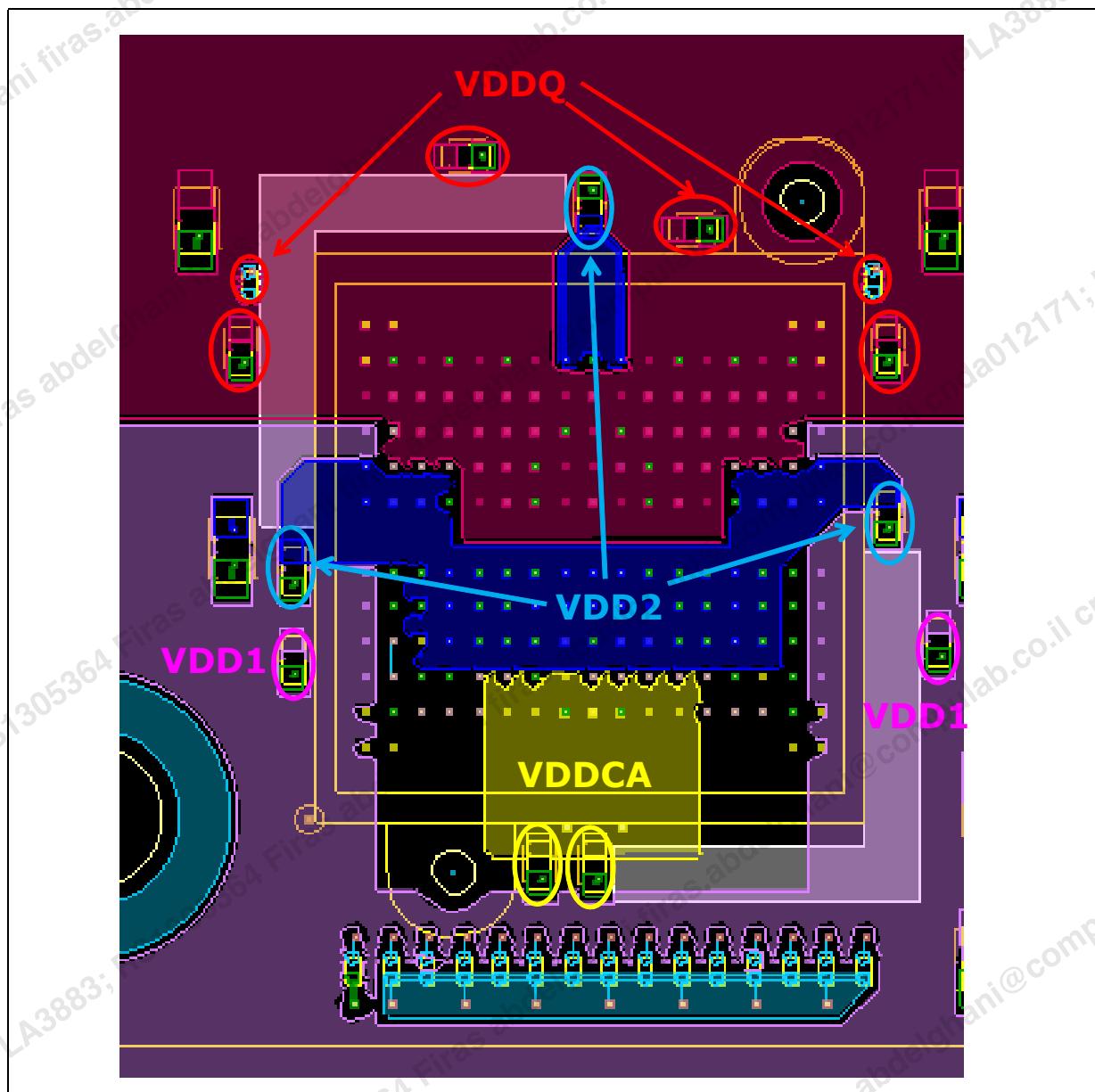
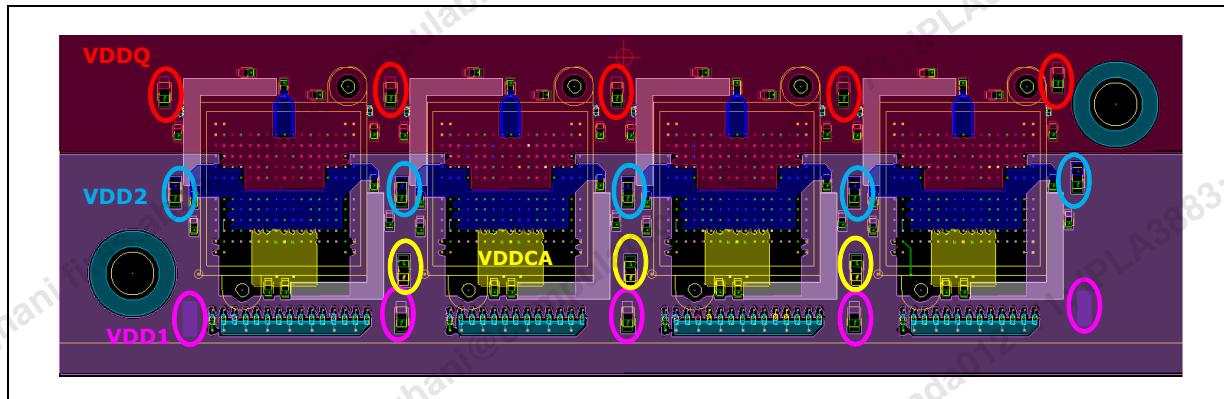
Figure 4-27. Decoupling at the LPDDR3 device

Figure 4-28. Decoupling at the LPDDR3 Device



§ §

5

DisplayPort® Design Guidelines

5.1

Introduction

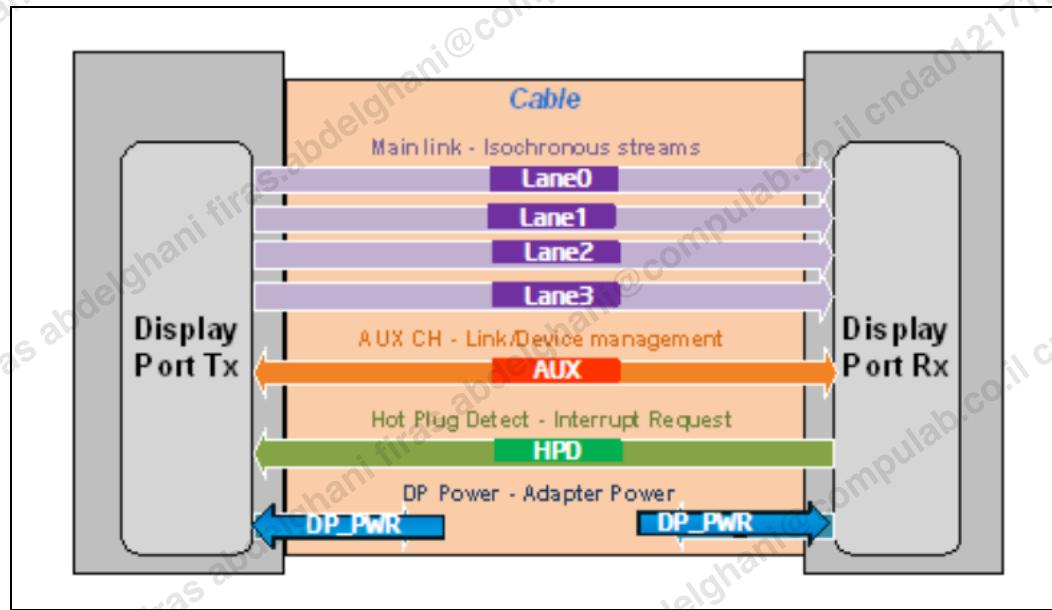
DisplayPort® uses differential signaling to achieve a high-bandwidth bus interface to support both embedded chip-to-chip and external box-to-box digital display connections from the Coffee Lake processor and PCH. A DisplayPort link consists of:

Main link: Unidirectional, high-bandwidth, and low latency channel used for transport of isochronous data streams such as uncompressed video and audio.

Auxiliary Channel (AUX CH): A half-duplex, bi-directional channel used for link and device control.

Hot Plug Detect (HPD) signal: Serves as an interrupt request for the sink device.

Figure 5-1. DisplayPort® Channels



5.1.1

DisplayPort® Link Bit Rates

DisplayPort® Main link uses a scrambled 8b/10b encoding scheme for the data stream being transmitted. It allows the clock to be embedded in the data stream.

Table 5-1.

DisplayPort® Bit Rates

Bit Rate	Supports (in # of lanes)	Peak Bandwidth
1.62 Gb/s	4	4 x 162 MB/s = 648 MB/s
2.7 Gb/s	4	4 x 270 MB/s = 1080 MB/s
5.4 Gb/s	4	4 x 540 MB/s = 2160 MB/s



5.1.2 DisplayPort® Main Link Buffer Type

The AC coupled External DisplayPort® (from the Coffee Lake processor) buffers are capable of driving the following voltage and pre-emphasis levels:

Table 5-2.

Supported Voltage and Pre-emphasis Levels

Nominal Voltage	Voltage Level	0 db	3.5 db	6 db	9.5 db
0.4V	0	YES	YES	YES	YES
0.6V	1	YES	YES	YES	
0.8V	2	YES	YES		
1.2V	3	NOT SUPPORTED			

The transmitter driver strength is optimized during the link training for Ext-DP. Pre-emphasis is an effective way to open the data eye of a high-loss channel. The longer trace length increase the channel interconnect loss and therefore require pre-emphasis. For more details on multiple pre-emphasis levels, refer to the DisplayPort® specifications.

5.1.3 Reference Documents

Title	Document Number/Location
DisplayPort Standard Version 1.2 Electrical Specification	http://www.vesa.org
VESA DisplayPort Dual-Mode Standard	
High speed internal connector and cable specification	549136

5.2 DisplayPort® Signal Descriptions

5.2.1 Signal Groups

Table 5-3. DisplayPort® Signals

Description	Signal Mapping		
	Coffee Lake Processor	Cannon Lake PCH	CRB DisplayPort Mapping
Main Link (Tx)	DDIx_TXP[3:0] and DDIx_TXN[3:0]	N/A	DDIx_OB_LANE[3:0]_DP and DDIx_OB_LANE[3:0]_DN
Aux Channel	DDIx_AUXP and DDIx_AUXN	N/A	DDIx_OB_AUX_DP and DDIx_OB_AUX_DN
Hot Plug Detect	N/A	DDPx_HPD[3:0]	DDIx_HPD_Q
Topology		Differential-Pair Point-to-Point Single Ended Point-to-Point	
Reference Plane	Ground Referenced		



5.3

DisplayPort® Topology Guidelines

For all topologies, the sink connects to the source via a cable. It is useful to partition the system budgets across the platform components, source, cable assembly and sink to allow different design teams a working budget. The design guide and resulting recommendations were designed to comply with the requirements for DisplayPort® mid bus probe point TP2 for HBR (High Bit Rate =2.7 Gbps) and RBR (Reduced Bit Rate =1.62Gbps). The compliance point for HBR2 (High Bit rate 2 =5.4Gbps) is TP3_EQ.

DisplayPort® Main and Aux Link Topologies:

- CFL DisplayPort® Main Link on Motherboard Topology
- CFL DisplayPort® Main Link Muxed Port Sharing on Motherboard Topology
- CFL DisplayPort® Main Link on Dock Topology with Re-driver
- CFL DisplayPort® Main Link Muxed Port Sharing on Dock Topology
- CFL DisplayPort® Main Link Internal Cable Topology

Note:

In addition to the routing design details mentioned below, refer to the DisplayPort external cable requirement in the [VESA DisplayPort Standard](#).

5.3.1

Optimizations

Table 5-4. Optimization Table for all Topologies

Description	Recommendation	Value (Units)
BO/M1	The traces BO/M1 constitute a breakout and a main route segment pairing. The segments of this pair must be routed on the same layer.	
AC Capacitor	Select the AC Capacitor values as per DisplayPort 1.3 Electrical specifications	nominal 100 nF recommended (tolerance 75 nF to 200 nF)
ESD/CMC	Recommended PCB CMC or Murata NFP0QHB372HS2. Refer to Section 49.6, "PCB CMC Technology" for more information.	
DP_PWR	DP_PWR provides power to the dongle. It is a 3.3-V rail on pin 20 of the DP connector.	
CFL H PTPS	CFL H uses 12mils Pair to Pair Spacing for equivalent main routing, and 15 mils for Non-Equivalent main routing. (For Equivalent & Non-Equivalent pairs see Ch.2)	
Inter-pair length mismatch	maximum length mismatch between the shortest and longest DP differential pairs for each port is 2"	
Inter-pair skew requirement	For Display Port signals is +/-1"	
CMC	All DP topologies in this chapter support CMC. CMC is optional and depends on the EMI testing results. It is recommended to leave the footprints in layout. Adding CMC will not reduce the supported length. If populated, reduce total route length by 1".	
Docking Topologies Only		
AC Cap1	AC Cap1 may be required based on the input requirements of your Re-driver. AC Cap1 can also be placed on motherboard.	
Re-driver	Re-driver assumed to consist of an ideal CTLE.	

5.3.2 DisplayPort* Main Link Motherboard Topologies

Figure 5-2. CFL DisplayPort* Main Link Direct Motherboard Topology

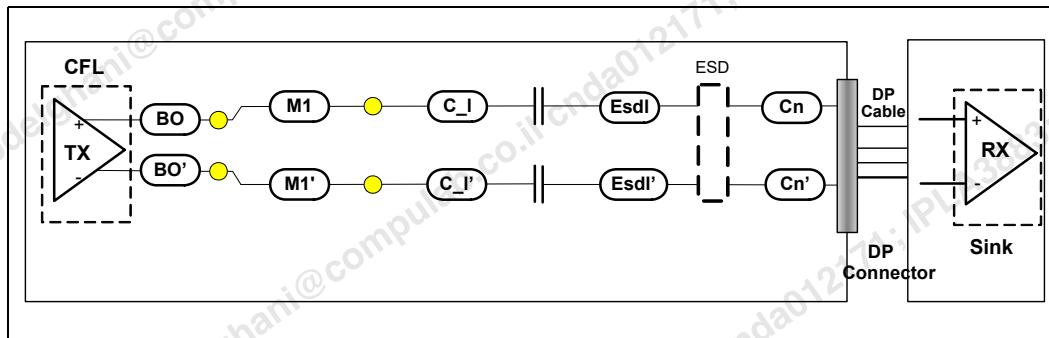


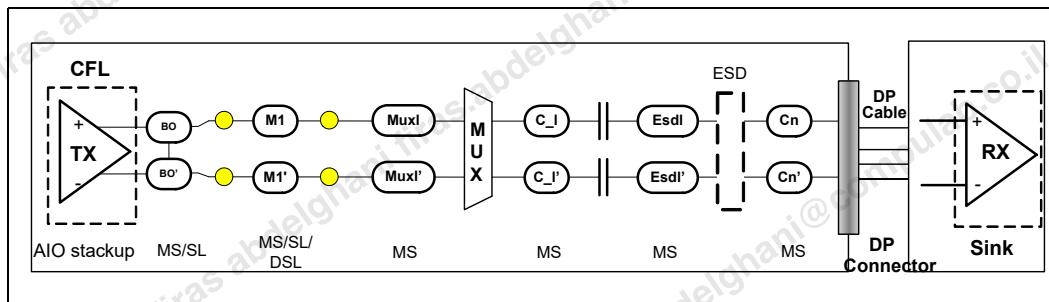
Table 5-6. CFL H Display Port Main Link Topologies Guidelines

Segment	Via Count	Stack-up	Max Length [mils]
B0	Max 2 vias are allowed	MS/SL	500
M1 + C_I		MS/SL/DSL	6500
Esdl		MS	300
Cn		MS	700
Total Length		6900	

Notes:

1. Reference plane will be Continues GND or Power. GND is preferred.
2. CMC is optional. If populated, reduce total route length by 1".

Figure 5-3. CFL H DisplayPort* Main Link Muxed Port Sharing Topology



5.3.3 Display Port® Main Link on Dock Topology with Redriver Topologies

Table 5-8. CFL H DisplayPort® Main Link Muxed Port Sharing Topology Guidelines

Segment	Stack-up	Via Count	Max Length [mils]
B0	MS/SL	Max 2 vias are allowed	500
M1	MS/SL/DSL		2200
Muxl	MS		300
C_I	MS		700
ESDL	MS		300
Cn	MS		700
Total Length			4100

Notes:

1. DP to VGA converter must meet DP spec
2. Converter to connector must follow Vendor application note.

Figure 5-4. CFL H DisplayPort® Docking Topology with Re-driver

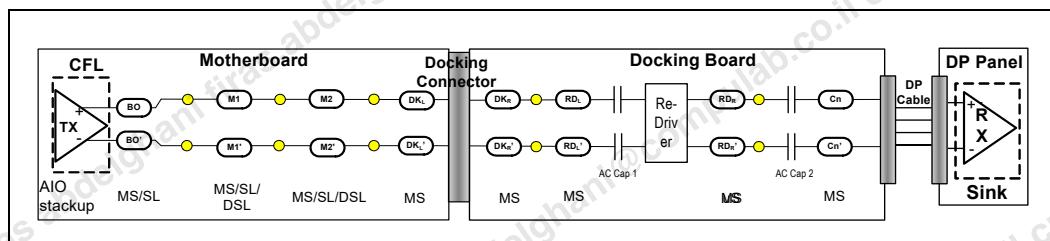
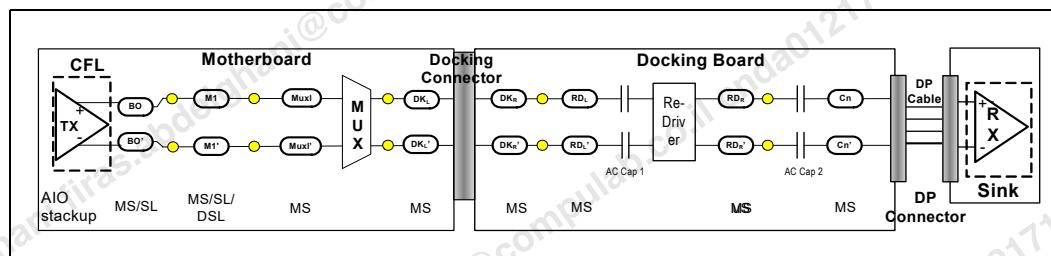


Table 5-9. CFL H DisplayPort® Docking Topology with Re-driver Guidelines (Sheet 1 of 2)

Segment	Stack-up	Max Length [mils]
BO	MS/SL	500
M1+M2	MS/SL/DSL	4000
DKL	MS	700
DKR	MS	3000
RDL	MS	300
RDR	MS	1500
CN	MS	500
Total Length		10800
Total Length --> BO to RDL		8800
Total Length --> DKR to CN		5300

Table 5-9. CFL H DisplayPort® Docking Topology with Re-driver Guidelines (Sheet 2 of 2)

Segment	Stack-up	Max Length [mils]
Notes:		
1.	AC Cap1 may be required based on the input requirements of your Re-driver	
2.	Re-driver assumed to consist of ideal CTLE, re-timing not necessary.	
3.	Docking topology does not require retimed redriver (jitter cleaning redriver).	

Figure 5-5. CFL H DisplayPort® Main Link Multiplexed Port Sharing on Dock Topology

Table 5-10. CFL H DisplayPort® Multiplexed Docking Topology with Re-driver Guidelines

Segment	Stack-up	Max Length [mils]
BO	MS/SL	500
M1	MS/SL/DSL	4000
MUXL	MS	300
DKL	MS	700
DKR	MS	3000
RDL	MS	300
RDR	MS	1500
CN	MS	500
Total Length		10800
Total Length --> BO to RDL		8800
Total Length --> DKR to CN		5300

Notes:

1. AC Cap1 may be required based on the input requirements of your Re-driver
2. Re-driver assumed to consist of ideal CTLE, re-timing not necessary.
3. Docking topology does not require retimed redriver (jitter cleaning redriver).

5.3.4 Display Port® Main Link Internal Cable Topology

Figure 5-6. CFL H DisplayPort® Main Link Internal Cable Topology

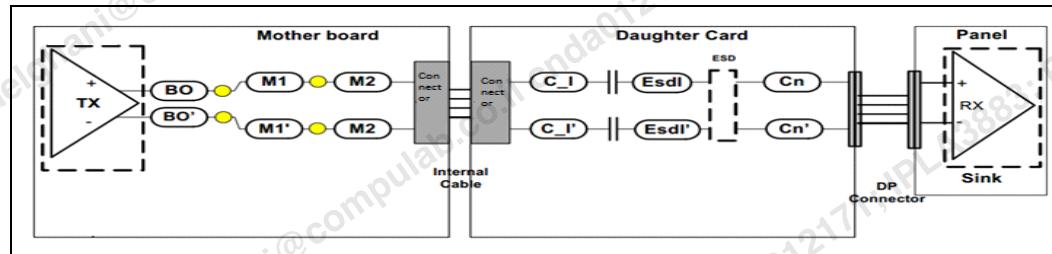


Table 5-11. CFL H DisplayPort® Main Link Internal Cable Topology Guidelines

Segment	Stack-up	Max Length [mils]								
		400	400	400	400	400	400	400	400	400
BO	MS/SL	400	400	400	400	400	400	400	400	400
M1	MS/SL/DSL	5500	5000	4500	4000	3500	3000	2500	2000	
M2	MS	500	500	500	500	500	500	500	500	500
BO+M1+M2	-	5500	5000	4500	4000	3500	3000	2500	2000	
EsdI	MS	100	100	100	100	100	100	100	100	100
C_I+EsdI+Cn	MS	800	800	800	800	800	800	800	800	800
Cable Loss @ 2.7GHz	-	<=1.3dB	<=1.8dB	<=2.2dB	<=2.5dB	<=2.7dB	<=2.9dB	<=3.2dB	<=3.4dB	
Informative AWG38 100W Microcoax	-	2000	5800	8900	11200	12800	14300	16700	17700	
Notes:										
1. Internal Cable far end crosstalk should be <=-54dB @ 2.7GHz										
2. Pair to pair spacing for motherboard and daughter card is 15 mils.										

5.3.5 DisplayPort* Auxiliary Channel Topologies

DisplayPort auxiliary channel is a sideband bidirectional differential communication channel. The channel is used by the Source to Discover Sink Capabilities and to determine the multi stream topology during link training. During normal operation, the channel is used to maintain the link, to transport auxiliary data, and control the Display.

Refer the respective stack-up sections for corresponding trace geometries.

Note:

Refer the latest [VESA DisplayPort Standard](#) for any updates to the specification and topologies.

Figure 5-7. CFH H DisplayPort* Auxiliary Channel External (Topology A)

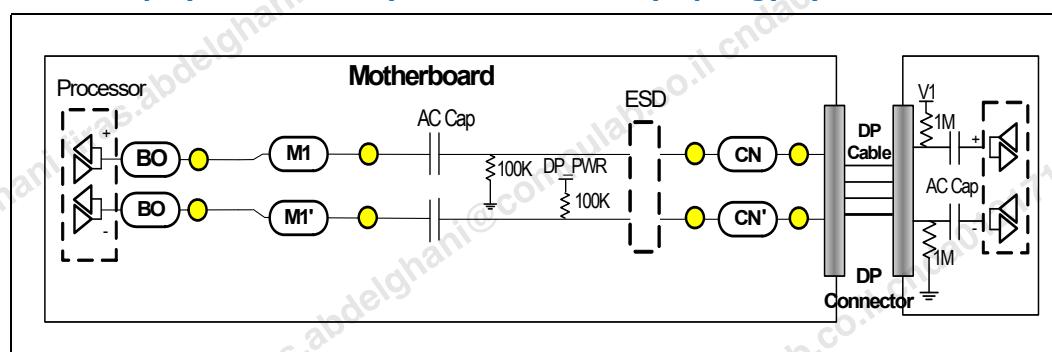


Figure 5-8. CFH H DisplayPort* Auxiliary Channel Multiplexed Port Sharing on Motherboard (Topology B)

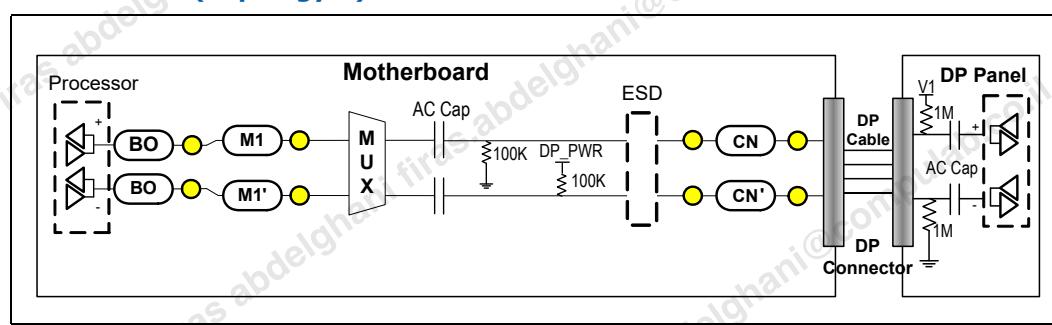


Figure 5-9. CFH H DisplayPort* Auxiliary Channel Docking with Re-driver Aux Sampling (Topology C)

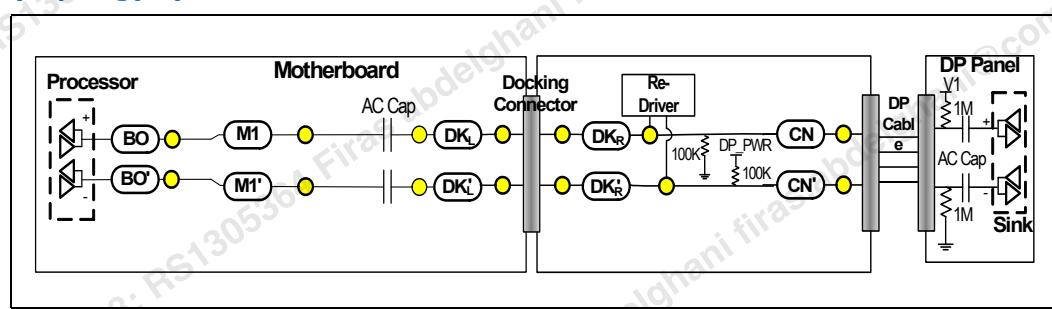


Figure 5-10. CFH H DisplayPort® Auxiliary Channel Docking with Re-driver Aux Buffer (Topology D)

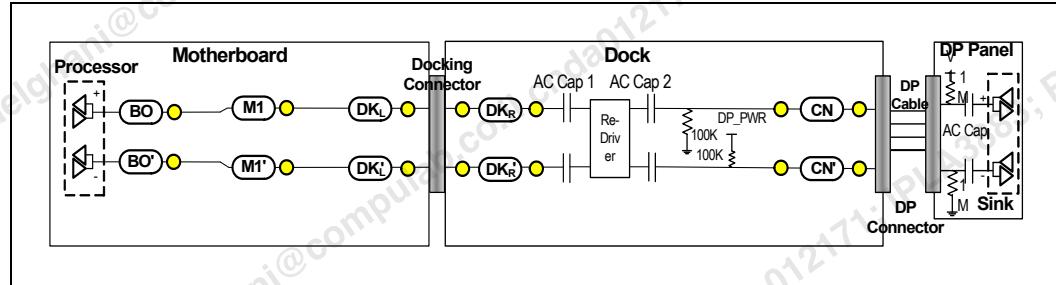


Figure 5-11. CFL H DisplayPort® Auxiliary Channel Internal Cable

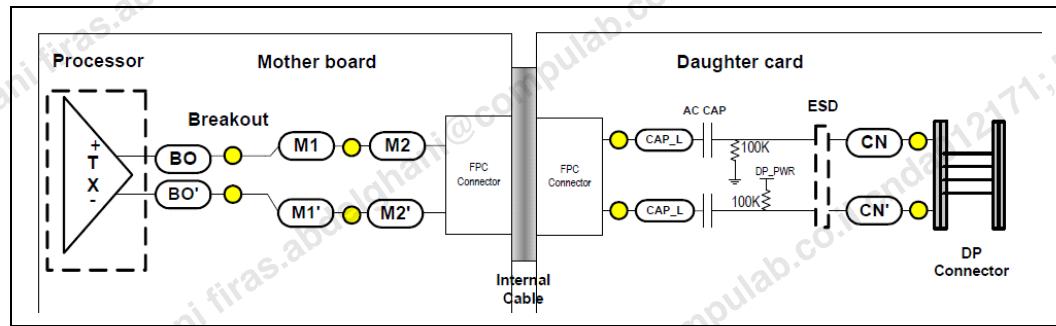


Table 5-13. CFL H DisplayPort® Auxiliary Channel Routing Guidelines (Sheet 1 of 2)

Parameters	Segment	Stackup	Units	Topology A and B	Topology C and D	Internal Cable
Coffee Lake Processor Breakout1 Max	BO	MS/SL	mils	800	700	NA
Main Route Segment Length Max	M1	MS/SL/DSL	mils	7000	5000	NA
ESD to DP Connector Length Max	CN	MS/SL/DSL	mils	7000	4000	NA
Total Motherboard Trace Length	Sum (BO to CN)	NA	mils	13000	NA	NA
Total Motherboard Trace Length	Sum (BO to DK _L)	NA	mils	NA	8000	NA
Docking Connector to Re-Driver Input	DK _R	MS	mils	NA	4000	NA
Total Route on the Dock Length Max	DK _R + CN	NA	mils	NA	7000	NA
Total Route from Coffee Lake Processor to DP Connector	Sum (BO to CN)	NA	mils	13000	14000	13000
Via usage Max (Dock Connector to DP Connector)	DK _R +CN (including breakout)	NA	vias	NA	3	NA

Table 5-13. CFL H DisplayPort® Auxiliary Channel Routing Guidelines (Sheet 2 of 2)

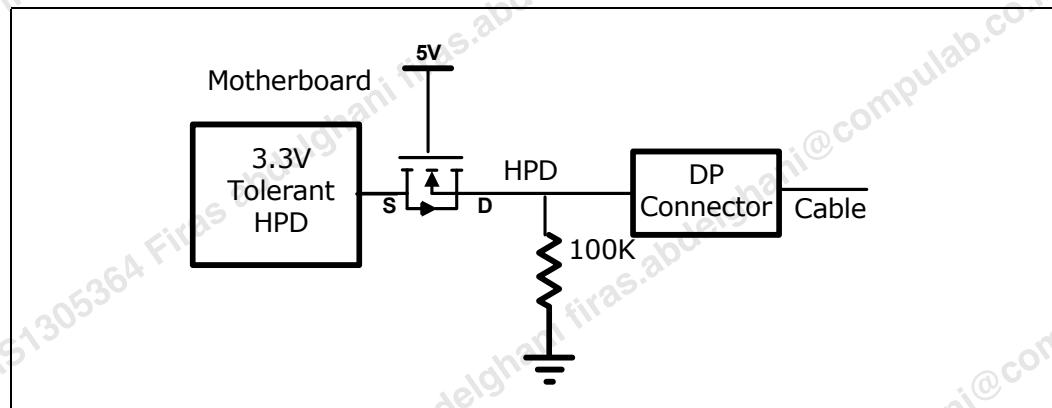
Parameters	Segment	Stackup	Units	Topology A and B	Topology C and D	Internal Cable
Notes:						
1.	ESD is recommended to protect the silicon host and devices from electrostatic discharges. Refer to Optimization Table for specific passive devices and other common topology requirements.					
2.	If total length of Aux signals is less than max allowed length of DP main link signals, then Aux main route can use 12 mils Pair To Pair Spacing, otherwise Aux Pair To Pair Spacing needs to be 15mils					

5.4 DisplayPort® General Considerations and Optimization

5.4.1 DisplayPort® HPD General Considerations and Optimization

The hot-plug detect output from DisplayPort sink device is a 3.3-V active high signal. Since the input on Coffee Lake processor is also 3.3-V tolerant, no inverting level shifter is required on the motherboard. However, a current blocking circuit (for example using a FET) is required to prevent the back drive current damaging Coffee Lake processor when the source is powered off and sink device is powered on. The following figure shows an example of this implementation.

Note: If the display connector is on the docking station, the hot-plug circuitry should remain on main motherboard and not on the docking station in order to prevent display detection failures related to hot-plug and S-state resume. HPD signal should not be allowed to float anytime.

Figure 5-12. DisplayPort® HPD Passgate Design Recommendation


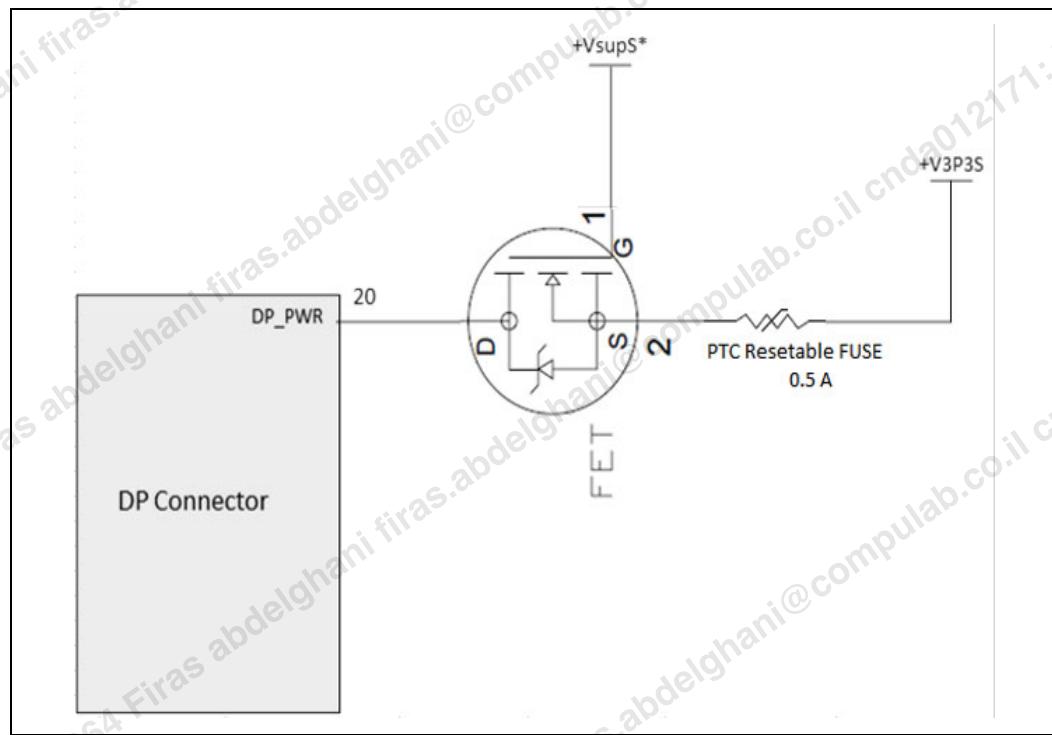
Note: Select the pass-gate FET which has $V_{GS\text{TH}}$ (Gate Threshold voltage) less than 1.5V. The 5V supply must turn off when CPU power is turned off.

5.4.2 DP_PWR Pin Back Drive Protection

DP_PWR pin 20 of DP Connector provides power to the connected dongle from the platform (source) and monitor (sink). As per specification, Normal DP to DP monitor cable assembly should not connect this across the cable. There are non-compliant cables in the market have them as direct connection. This results in Display monitor back driving current to motherboard and causing system malfunction during power on or when waking-up from sleep state.

To prevent this, add a back driver protection circuit (FET) as shown below for DP_PWR pin 20 of DP connector. FUSE is also provided to provide current protection as required by DP spec. Select MOSFET such that sum of Fuse and MOSFET 's ON resistance is less than 0.35 ohms to meet spec requirement of minimum 2.98Volts at DP_PWR pin with 0.5A current.

Figure 5-13. DisplayPort® DP_PWR pin 20 Back Drive Protection



Note:

Connect Gate of n-MOSFET to a power supply which will turn off during sleep state and is higher than 3.3V like +V12S or +V5S.

Note:

Customer can have alternate back drive protection circuit provided they can meet minimum Voltage requirement of 2.98Volts considering 3.3Volts power supply design also have some voltage tolerance(+/-5%).



5.4.3

DisplayPort® Main Link Differential-Pair Width and Spacing

Type 3 and Type 4 stack-up geometries will be different. For a summary of general routing guidelines for the width and spacing of the differential-pair traces, refer Chapter 2 “Stack-up and PCB Considerations”.

5.4.4

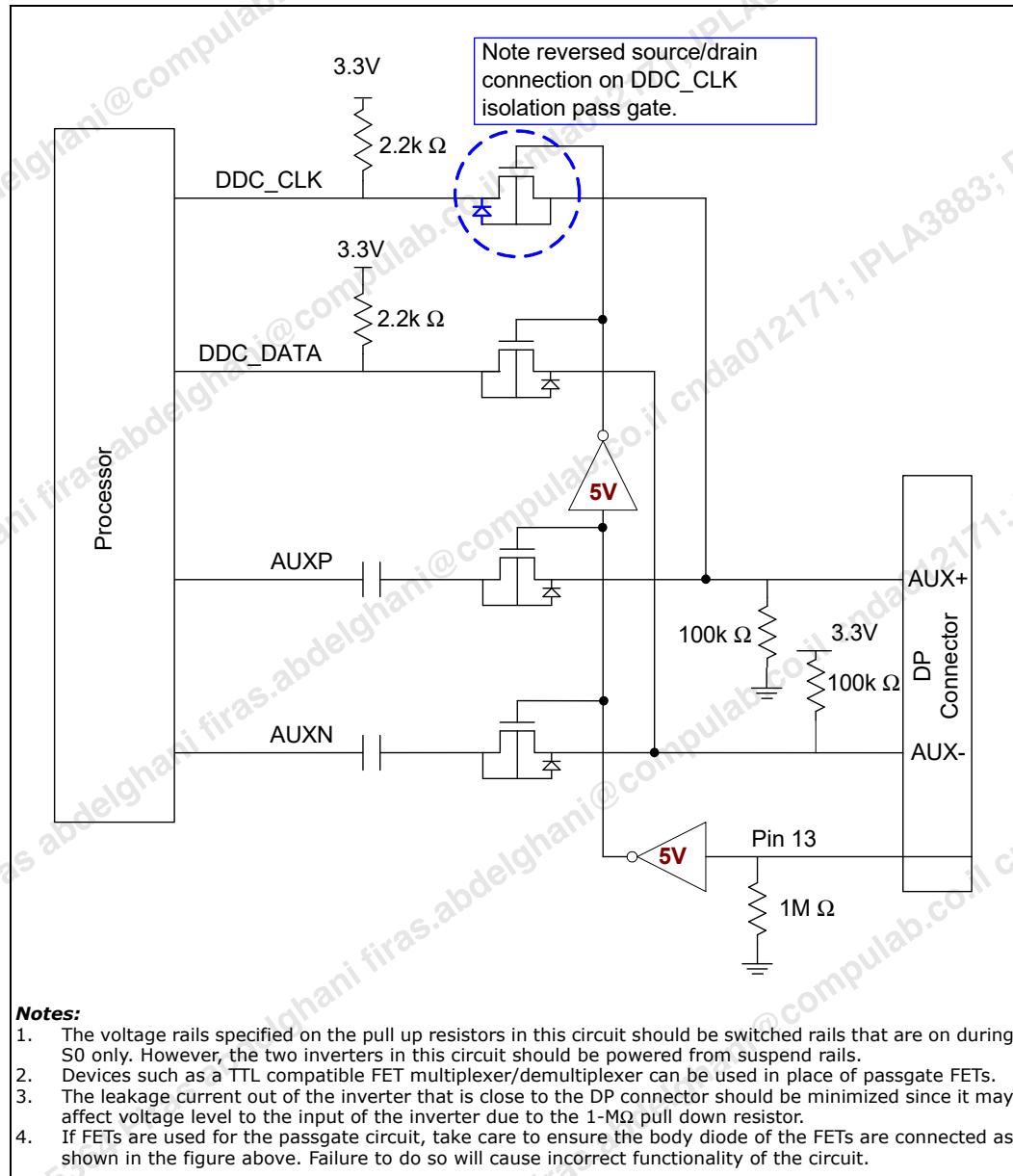
DisplayPort® Auxiliary Channel (AUX CH) General Design Considerations and Optimization

AUX CH consists of an AC-coupled, bi-directional differential-pair, providing a data rate of 1 Mbps. It is used for link management and device control, that is, for transmitting control and status information.

AUX CH is half-duplex and bi-directional. The source device is the master and Sink device is the slave. Manchester II coding is used as the channel coding for AUX CH. Like the Main link the Aux Channel clock is embedded in the data stream.

The sink device may toggle the HPD signal to interrupt the source device.

To support dual mode (DP++) over DisplayPort through Dongle for HDMI, the circuit shown below is required to be implemented on the motherboard.

Figure 5-14. DisplayPort® Auxiliary Channel Dual Mode Support Protection Circuit



5.5

DisplayPort* Length Matching Guidelines

For matching methodology, refer Chapter 3, "General Differential Design Guidelines".

5.6

Digital Display Interface Disabling and Termination Guidelines

All the digital display ports on the Coffee Lake processor have a strap associated with it. The port strap needs to be set to configure each digital port irrespective of the digital display technology HDMI/DP. The following table lists all the digital display straps and guidelines to enable/disable a respective port on the platform. All the straps are sampled on the rising edge of the PWROK signal.

Table 5-14. DDI Disabling and Termination Guidelines

Port	Strap	How to Enable Port	How to Disable Port
Port 1	DDPB_CTRLDATA	Pull up to 3.3V with 2.2K ohm ±5% resistor	No Connect
Port 2	DDPC_CTRLDATA	Pull up to 3.3V with 2.2K ohm ±5% resistor	No Connect
Port 3	DDPD_CTRLDATA	Pull up to 3.3V with 2.2K ohm ±5% resistor	No Connect

The following table lists connection details for the digital display signals when Coffee Lake processor graphics is disabled. When Coffee Lake processor graphics is not implemented on the platform, the digital display interface must also be disabled in BIOS. Refer to the BIOS specification on how to disable the respective display interfaces.

Table 5-15. DDI Disabling and Termination Connections

Pin Name	Recommendation
DDPB_AUXP / DDPC_AUXP / DDPD_AUXP	No Connect
DDPB_AUXN / DDPC_AUXN / DDPD_AUXN	No Connect
DDPB_HPD / DDPC_HPD / DDPD_HPD	No Connect
DDI1_TXP[3:0] / DDI2_TXP[3:0] / DDI3_TXP[3:0]	No Connect
DDI1_TXN[3:0] / DDI2_TXN[3:0] / DDI3_TXN[3:0]	No Connect
DDPB_CTRLCLK / DDPB_CTRLDATA	No Connect
DDPC_CTRLCLK / DDPC_CTRLDATA	No Connect
DDPD_CTRLCLK / DDPD_CTRLDATA	No Connect

5.7

Display Compensation Guidelines

Refer to Section 5.5, "DisplayPort* Length Matching Guidelines" for details.

Note:

There is one comp pin that is shared among all display ports.

Note:

Type-C DP implementation is covered under "18.4 Alternate Modes Configuration"

§ §



6

Embedded DisplayPort* (eDP*) Design Guidelines

The Embedded DisplayPort* (eDP*) channel is used to transport digital display data from the Coffee Lake processor to an embedded DisplayPort Panel. Embedded DisplayPort (eDP) utilizes differential signaling to achieve a high bandwidth bus interface that supports embedded chip-to-chip connections from the Coffee Lake processor. Potential embedded chip-to-chip applications include usage within a laptop PC for driving a panel.

The Embedded DisplayPort utilizes DisplayPort 1.62 Gbps, 2.7 Gbps and 5.4 Gbps differential signaling. It is recommended that the eDP/DP standard TP3 EYE mask requirements as are met at the panel side of the mated connector.

Table 6-1. eDP* Reference Specification

Title	Location
VESA Embedded DisplayPort Standard - Revision 1.4	http://www.DisplayPort.org

Table 6-2. eDP* Compliance Specification

Title	Location
VESA Embedded DisplayPort Source PHY Compliance Test Guideline - Version 1.0	http://www.vesa.org

6.1 Signal Descriptions

Table 6-3. eDP* Signal Groups

Parameters	Signal Mapping		
	Processor	PCH	CRB eDP* Connector
Main Link (Tx)	eDP_TXN/P[3:0]	N/A	EDP_TX[3:0]_DN/DP
Aux	EDP_AUXN/P	N/A	EDP_AUX_DN/DP
HPD	N/A	eDP_HPD	EDP_HPD_Q
RCOMP	DISP_RCOMP	N/A	DISP_COMP
Topology	Differential-Pair Point-to-Point. Single ended Point to Point		
Reference Plane	Ground Referenced		

6.2 Topology Guidelines

Table 6-4. eDP* Cable Parameters (Sheet 1 of 2)

Cable	Cable Length	Connector Pitch	Cable AWG	Diff Impedance	Diff Insertion Loss	Diff Return Loss	Diff FEXT	EMI/RFI	HBR2/HBR
Micro-Coax	1"	1 mm	40	85-110 Ω	-0.8db/-1db/-1.7db/-5.4db	-12.8db/-16.5db/-26db/-4db	-47.2db/-39db/-30db/-36db	LOW	HBR2/HBR recommended

**Table 6-4. eDP* Cable Parameters (Sheet 2 of 2)**

Cable	Cable Length	Connector Pitch	Cable AWG	Diff Impedance	Diff Insertion Loss	Diff Return Loss	Diff FEXT	EMI/RFI	HBR2/HBR
Micro-Coax	3"	1 mm	40	85-110 Ω	-1.15db/-2.2db/-3.1db/-7.3db	-16.5db/-9.4db/-15.6db/-4.8db	-49.5db/-41.5db/-32db/-36.8db	LOW	HBR2/HBR recommended
Micro-Coax	4"	1 mm	40	85-110 Ω	-1.5db/-2.55db/-3.8db/-7.1db	-12.8db/-10.1db/-22db/-9.1db	-45.5db/-42.5db/-33db/-34.5db	LOW	HBR2/HBR recommended
Micro-Coax	5"	1 mm	40	85-110 Ω	-1.57db/-2.75db/-4.5db/-9.1db	-22.7db/-13.5db/-16.5db/-5.5db	-48db/-42.5db/-33.5db/-38db	LOW	HBR2/HBR recommended
Micro-Coax	6"	1 mm	40	85-110 Ω	-1.97db/-3db/-5.2db/-9.1db	-12.7db/-20.5db/-17.5db/-9db	-47.3db/-42.5db/-34db/-37.4db	LOW	HBR2/HBR recommended
Micro-Coax	8"	1 mm	40	85-110 Ω	-2.35db/-4db/-6.6db/-11.25db	-14.6db/-12.5db/-17db/-8.4db	-50db/-42.5db/-35db/-40db	LOW	HBR2/HBR recommended
Micro-Coax	12"	1 mm	40	85-110 Ω	-3.2db/-5.4db/-9.4db/-15.3db	-20.25db/-17db/-18.25db/-7.6db	-49db/-45db/-40db/-44.5db	LOW	HBR2/HBR recommended
Micro-Coax	18"	1 mm	40	85-110 Ω	-4.5db/-7.5db/-13.6db/-21db	-23.6db/-17.8/-20.5/-6.5db	-47.2db/-45db/-39db/-43db	LOW	HBR2/HBR recommended

Notes:

1. Differential Insertion Loss, return loss and FEXT values are based on current eDP* channel electrical analysis.
2. Differential Insertion Loss, return loss and FEXT parameters above are for 1.35 GHz / 2.7 GHz / 5.4 GHz / 8.1 GHz respectively

6.3 Optimizations

Table 6-5. Optimization Table for all Topologies

Description	Recommendation	Value (Units)
BO/M1	The traces BO/M1 constitute a breakout and a main route segment pairing. The segments of this pair must be routed on the same layer.	
Vias	Use of less number of vias is allowed provided the routing layer guideline for MS/SL/DSL is met	
CMC	Recommended PCB CMC or Murata NFP0QHB372HS2. Refer to Section 49.6, "PCB CMC Technology" for more information.	
AC CAP	AC caps are required to be placed before the motherboard eDP* connector	Main Link nominal 100nF recommended (tolerance 75–265 nF) Aux Channel nominal 100nF recommended (tolerance 75–200 nF)
CFL H PTPS	CFL H uses 12mils Pair to Pair Spacing for equivalent main routing, and 15 mils for Non-Equivalent main routing. (For Equivalent & Non-Equivalent pairs see Ch.2)	
Board type	For SL Breakout implementation please place the first via to the left of Breakout (BO) segment. Via BO is allowed to appear inside the BO main route but total length must meet PDG requirements.	
SL Breakout implementation		
Inter-pair length mismatch	Maximum length mismatch between the shortest and longest eDP* differential pairs for each port is +/-1"	



6.3.1 Coffee Lake Processor Graphics Embedded DisplayPort® Main Link Topology for HBR and HBR2

6.3.1.1 Main Link

Figure 6-1. CFL eDP® Main Link Direct Topology

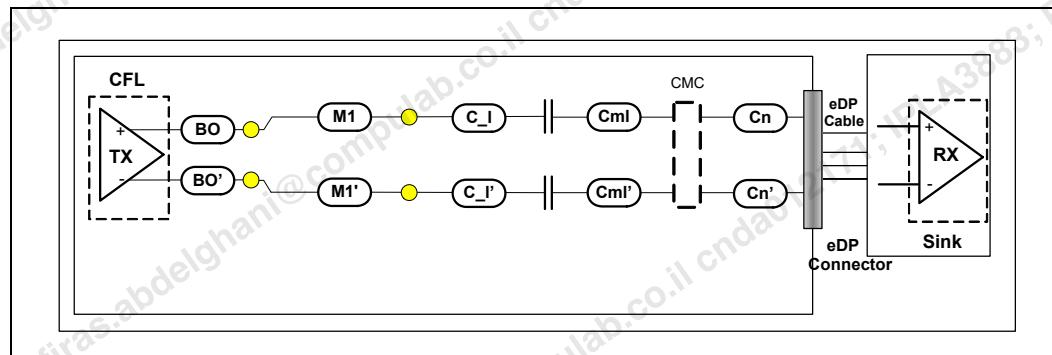


Table 6-6. CFL eDP® Main Link Topology for HBR and HBR2

Segment	Stack-up	Via Count	Max Length [mils]		
B0	MS/SL	Max 2 vias are allowed	500		
M1	MS/SL/DSL		1000 - 8000		
C_I	MS		100		
CmI'	MS		1000		
Cn	MS		500		
Total Length		2000 - 10000			
eDP® Cable Length		4000 - 15000			
Note:					
1. Reference plane will be Continues GND or Power. GND is preferred.					

6.3.1.2 Auxiliary Channel

Figure 6-2. CFL eDP* Auxiliary Channel Topology

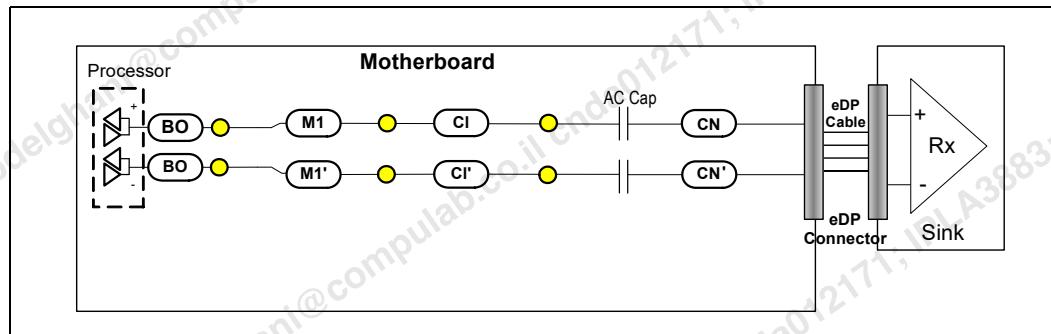


Table 6-7. CFL eDP* Main Link Auxiliary Channel Topology

Segment	Stack-up	Via Count	Max Length [mils]
B0	MS/SL	Max 2 vias are allowed	700
M1	MS/SL/DSL		10000
CI	MS		10000
CN	MS		750
Total Length			10000
eDP* Cable Length			4000 - 15000

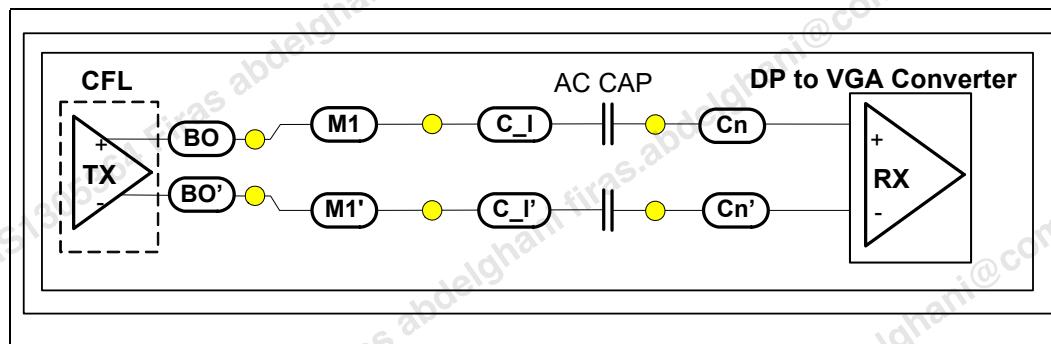
Note:
1. Reference plane will be Continues GND or Power. GND is preferred.

Note: Reference plane will be Continues GND or Power. GND is preferred.

6.3.2 Embedded DisplayPort* to VGA Main Link Topology

6.3.2.1 Main Link

Figure 6-3. CFL eDP* Main Link Direct DP to VGA Topology



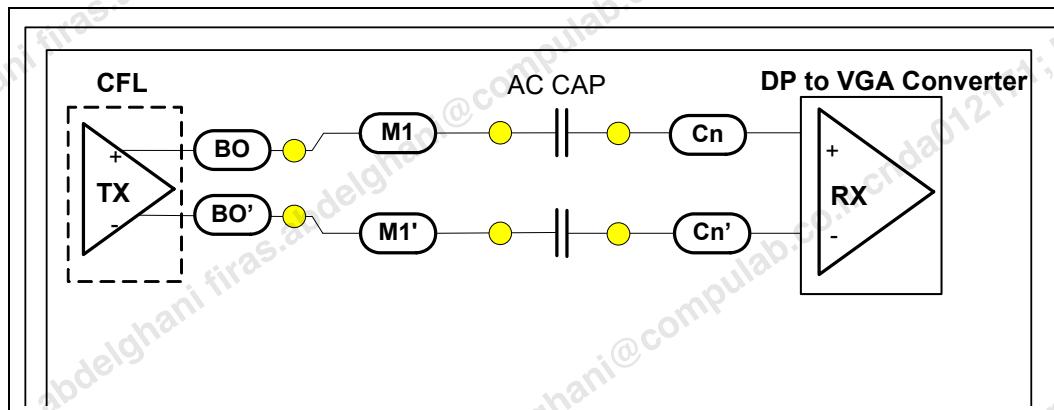
**Table 6-8. CFL H Display Port Main Link Direct DP to VGA Topology**

Segment	Stack-up	Via Count	Max Length [mils]
B0	MS/SL	Max 2 vias are allowed	500
M1 + C_I	MS/SL/DSL		6500
Cn	MS		1000
Total Length			6900

Notes:

1. DP to VGA converter must meet DP spec
2. Converter to connector must follow Vendor application note.

6.3.2.2 Auxiliary Channel

Figure 6-4. CFL eDP® Aux Channel DP to VGA Converter Topology A**Table 6-9. CFL eDP® Aux Channel DP to VGA Converter Topology**

Segment	Stack-up	Via count	Max Length [mils]
B0	MS/SL	Max 2 vias are allowed	700
M1 + C_I	MS/SL/DSL		7000
Cn	MS		7000
Total Length			13000

Notes:

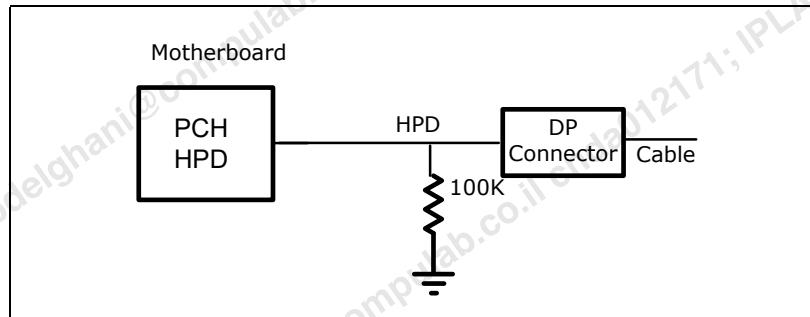
1. DP to VGA converter must meet DP spec
2. Converter to connector must follow Vendor application note.

6.3.3 Embedded DisplayPort® Hot-Plug Detect Implementation

Hot-plug detect (HPD) is an output from eDP® sink device and it is a active high signal.

Note:

When using eDP bifurcation for DP-VGA Topology, need to use HPD for DDIE (DDPE_HPD) for HPD connectivity.

Figure 6-5. Embedded DisplayPort* HPD Signal

6.4 Length Matching Guidelines

For matching methodology, refer to General Differential Design Guidelines chapter Chapter 3, "General Differential Design Guidelines".

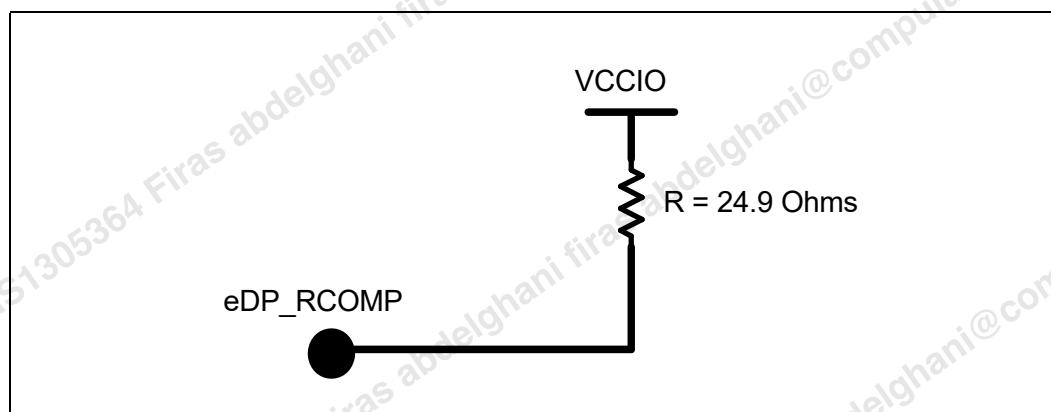
6.5 Digital Display Interface Compensation Guidelines

The compensation input is used by the circuitry to determine, check and adjust the system buffer output strength and characteristic impedance over temperature, process and voltage variations. This is done by comparing its buffer impedance against a standard reference resistor, RCOMP.

Note:

The RCOMP signals should be referenced to Vss and noisy or switching references should be avoided. As board space allows, recommend to add a VSS shield at least 4 mils wide placed between RCOMP and adjacent IO.

Coffee Lake processor signal DISP_RCOMP should be connected to the VCCIO rail via a single $24.9 \pm 1\%$ Ω resistor. DISP_RCOMP is DDI I/O compensation resistor which supports DP, eDP* and HDMI* channels.

Figure 6-6. Embedded DisplayPort* Compensation Signal Routing Topology



6.5.1 Compensation Signal Routing Guidelines

Table 6-10. DISP_RCOMP Guideline

Signal	Min Trace Width	Isolation Spacing	Resistor Value	Max Length
DISP_RCOMP	5 mils	20 mils	24.9 Ω ±1%	600 mils
Note: Must maintain low DC resistance routing (<0.1Ω)				

6.5.2 Disabling and Termination Guidelines

Table 6-11. eDP® Disabling and Termination Guidelines

Pin name	Recommendation
eDP_TXN/P[3:0]	No connect
EDP_AUXN/P	No connect
eDP_HPD	Pull down to ground via 100k Ω resistor
DISP_RCOMP	Pull up to VCCIO via 24.9 Ω resistor
eDP_DISP_UTIL	No connect

§ §

7

High-Definition Multimedia Interface* (HDMI*) Design Guidelines

The Integrated High-Definition Multimedia Interface* (HDMI*) transmits digital television audiovisual signals from DVD players, set-top boxes and other audiovisual sources to television sets, projectors and other video displays.

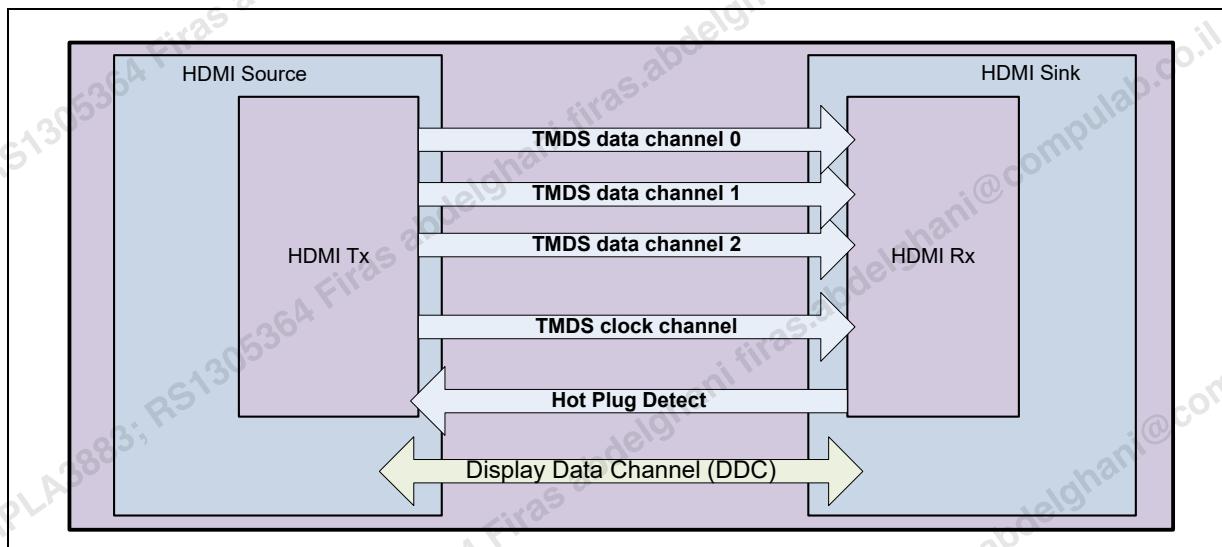
HDMI* is a display interface connecting the Coffee Lake processor and PCH with display devices that utilizes transition minimized differential signaling (TMDS) to carry audio-visual information through the same HDMI* cable.

7.1 Overview

HDMI* includes three separate communications channels: TMDS, DDC, and the optional CEC (consumer electronics control) however CEC is not supported. The data and clock channels are used to carry video, audio and auxiliary data. In addition, HDMI* carries a VESA display data channel (DDC). The DDC channel is used by an HDMI* source to determine the capabilities and characteristics of the sink.

Audio, video and auxiliary (control/status) data is transmitted across the three TMDS data channels. The video pixel clock is transmitted on the TMDS clock channel and is used by the receiver for data recovery on the three data channels.

Figure 7-1. HDMI* Overview





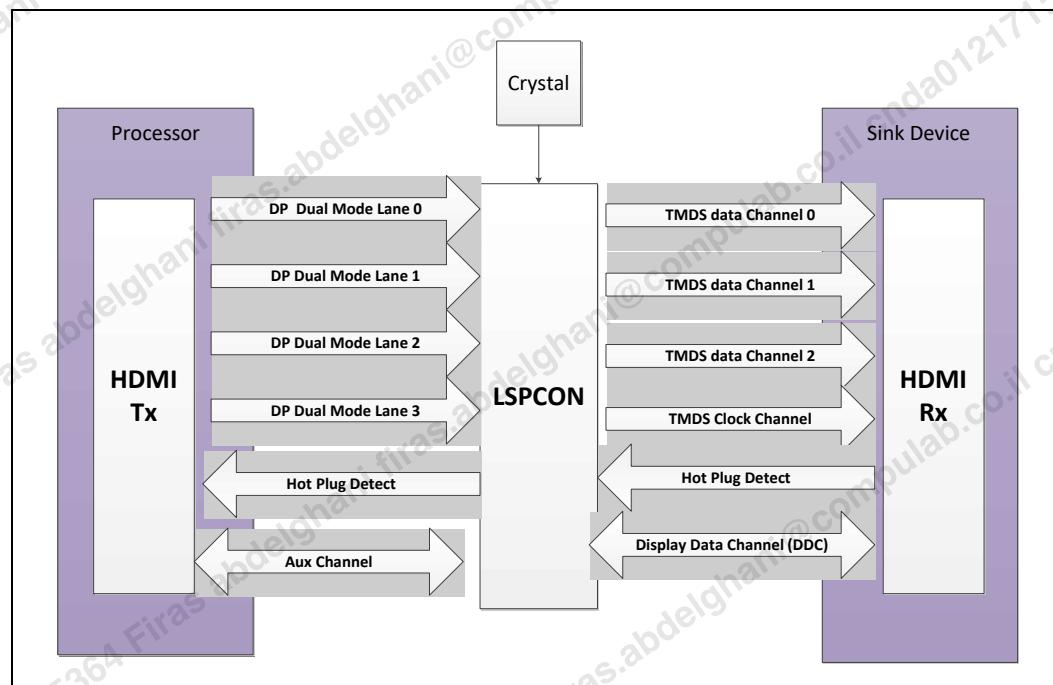
There are three digital display interface channels or ports available that can be configured as HDMI. Each channel or port of HDMI* is comprised of three differential data lanes, and an associated differential-clock, Hot Plug Detect signal (HPD) and two Display Data Channel (DDC) signals. The maximum data rate supported for HDMI* is 2.97 Gb/s for specific configurations.

In order to support HDMI* 2.0, we are adding an external DP-HDMI* 2.0 Level-Shifter/Protocol Converter (LS-PCon) device. The LS-PCon device contains two functions:

1. A DisplayPort* Dual-mode Type 2 Adaptor Function that supports HDMI* 1.4b up to 3.4 Gbps.
2. A DP Branch Device with a DP-to-HDMI2.0 Protocol Converter Function that supports HDMI* 2.0 up to 5.94 Gbps through protocol conversion from DP (HBR2) to HDMI* 2.0

This scheme is also backward compatible with HDMI* 1.4b spec with up to 2.97 Gb/s. The detailed protocol and electrical properties of this device can be found at Intel LSPCON specification.

Figure 7-2. HDMI* 2.0 Overview



**Table 7-1. Mapping of HDMI* Signals for DDI Ports**

Port	Digital Display Interface Pins	CRB Digital Display Interface Signals	HDMI* Signals
Port 1	DDI1_TXP[0]	DDI1_LANE0_DP	HDMIx_TX2_DP
	DDI1_TXN[0]	DDI1_LANE0_DN	HDMIx_TX2_DN
	DDI1_TXP[1]	DDI1_LANE1_DP	HDMIx_TX1_DP
	DDI1_TXN[1]	DDI1_LANE1_DN	HDMIx_TX1_DN
	DDI1_TXP[2]	DDI1_LANE2_DP	HDMIx_TX0_DP
	DDI1_TXN[2]	DDI1_LANE2_DN	HDMIx_TX0_DN
	DDI1_TXP[3]	DDI1_LANE3_DP	HDMIx_CLK_DP
	DDI1_TXN[3]	DDI1_LANE3_DN	HDMIx_CLK_DN
	Hot plug detect used by HDMI Port 1	DDPB_HPD	DDI1_HPD_Q
	HDMI DDC lines for Port 1	DDPB_CTRLCLK	DDI1_CTRL_CK
		DDPB_CTRLDATA	DDI1_CTRL_DATA
Port 2	DDI2_TXP[0]	DDI2_LANE0_DP	HDMIx_TX2_DP
	DDI2_TXN[0]	DDI2_LANE0_DN	HDMIx_TX2_DN
	DDI2_TXP[1]	DDI2_LANE1_DP	HDMIx_TX1_DP
	DDI2_TXN[1]	DDI2_LANE1_DN	HDMIx_TX1_DN
	DDI2_TXP[2]	DDI2_LANE2_DP	HDMIx_TX0_DP
	DDI2_TXN[2]	DDI2_LANE2_DN	HDMIx_TX0_DN
	DDI2_TXP[3]	DDI2_LANE3_DP	HDMIx_CLK_DP
	DDI2_TXN[3]	DDI2_LANE3_DN	HDMIx_CLK_DN
	Hot plug detect used by HDMI Port 2	DDPC_HPD	DDI2_HPD_Q
	HDMI DDC lines for Port 2	DDPC_CTRLCLK	DDI2_CTRL_CK
		DDPC_CTRLDATA	DDI2_CTRL_DATA
Port 3	DDI3_TXP[0]	DDI3_LANE0_DP	HDMIx_TX2_DP
	DDI3_TXN[0]	DDI3_LANE0_DN	HDMIx_TX2_DN
	DDI3_TXP[1]	DDI3_LANE1_DP	HDMIx_TX1_DP
	DDI3_TXN[1]	DDI3_LANE1_DN	HDMIx_TX1_DN
	DDI3_TXP[2]	DDI3_LANE2_DP	HDMIx_TX0_DP
	DDI3_TXN[2]	DDI3_LANE2_DN	HDMIx_TX0_DN
	DDI3_TXP[3]	DDI3_LANE3_DP	HDMIx_CLK_DP
	DDI3_TXN[3]	DDI3_LANE3_DN	HDMIx_CLK_DN
	Hot plug detect used by HDMI Port 3	DDPD_HPD	DDI3_HPD_Q
	HDMI DDC lines for Port 3	DDPD_CTRLCLK	DDI3_CTRL_CK
		DDPD_CTRLDATA	DDI3_CTRL_DATA

Table 7-2. HDMI* Interface Reference Documents

Title	Document Number/Location
High-Definition Multimedia Interface Specification Version 1.4b	http://www.hDMI.org
High speed internal Connector and Cable Specification	549136

**Table 7-3. HDMI* Interface Compliance Documents**

Title	Location
High-Definition Multimedia Interface Compliance Test Specification 1.4b	http://www.hDMI.org

7.2 Signal Description

Table 7-4. HDMI* Signals

Description	Signal Mapping		
	Processor	PCH	CRB HDMI* Connector
Main Link (Tx)	DDIx_TXP[3:0] and DDIx_TXN[3:0]	N/A	HDMIx_OB_DATA[2:0]_DP and HDMIx_OB_CK_DP HDMIx_OB_DATA[2:0]_DN and HDMIx_CK_DN
DDC	DDPx_CTRLCLK/CTRLDATA	N/A	DDIx_CTRL_CK/CTRL_DATA
Hot Plug Detect	N/A	DDPx_HPD	DDIx_HPD_Q

7.3 HDMI 1.4* Topology Guidelines

The following are the topologies supported for HDMI* Data and Clock:

- Cost Reduced Level Shifter Motherboard Topology for max data rate of 1.65Gb/s
- Active Level Shifter Motherboard Topology for max data rate of 2.97 Gb/s
- Active Level Shifter Docking Topology
- Active Level Shifter Docking Multiplexed Topology Internal Cabled Solution

7.3.1 Differential-Pair Width and Spacing

HDMI* supports MS/SL/DSL. Follow the guidelines in "Printed Circuit Board (PCB) Considerations".

7.3.2 Optimizations

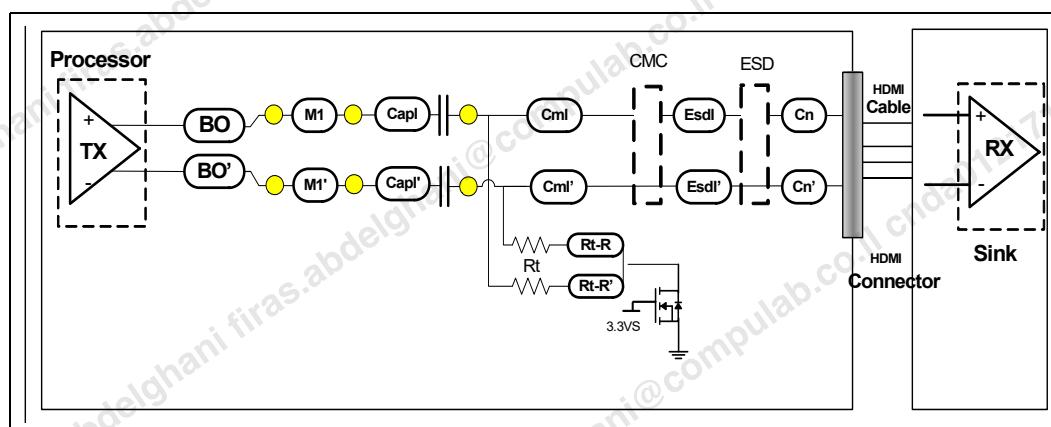
Table 7-5. Optimization Table for all Topologies (Sheet 1 of 2)

Description	Recommendation	
AC CAP	AC caps are required to be placed before the motherboard HDMI* connector	nominal 100nF recommended (tolerance 75-200 nF)
CN Via	The via before the CN segment is to enable backside entry of the connector. Intended to eliminate a stub on the through hole HDMI* connector.	
BO/M1	The traces BO/M1 constitute a breakout and a main route segment pairing. The segments of this pair must be routed on the same layer.	
Active Level Shifter (Tx/Rx)	Select the optimized receive and transmit equalization settings for the active level shifter to meet the compliance at the HDMI* connector.	
CMC	Recommended PCB CMC or Murata NFP0QHB372HS2. Refer to Section 49.6, "PCB CMC Technology" for more information.	
ESD		
DSL Routing	No broadside/parallel routing on the adjacent DSL layer on 8/10 layer stack-up	

Table 7-5. Optimization Table for all Topologies (Sheet 2 of 2)

Description	Recommendation
CFL H PTPS	CFL H uses 12mils Pair to Pair Spacing for equivalent main routing, and 15 mils for Non-Equivalent main routing. (For Equivalent & Non-Equivalent pairs see Ch.2)
SL Breakout (BO) implementation	For SL Breakout implementation please place the first via to the left of Breakout (BO) segment. Via BO is allowed to appear inside the BO main route but total length must meet PDG requirements.
Inter-pair length mismatch	maximum length mismatch between the shortest and longest HDMI* differential pairs for each port is 2"
Inter-pair skew requirement	For HDMI* signals is +/-1"

7.3.3 HDMI 1.4* Main Link Cost-reduced Level Shifter Topology

Figure 7-3. CFL HDMI 1.4* Main Link Cost-reduced Level Shifter Motherboard Topology

Table 7-6. CFL HDMI 1.4* Main Link Cost-reduced Level Shifter Motherboard Topology Guidelines

Segment	Via Count	CFL H	
		Stack-up	Max Length [mils]
B0	Max 3 vias are allowed	MS/SL	400
M1		MS/SL/DSL	constrained by total length
Capl		MS	100
Cml		MS	600
Esdl		MS	600
Cn		MS	600
Cml+Esdl+Cn		MS	600
Rt-R		MS	500
Total Length	6500		
Notes:			
1. Rt = 470ohm			
2. ESD is recommended. CMC is optional (recommended to leave footprint on platform)			
3. Any port configured to support HDMI must implement sideband communications via the DDC (I2C) channel associated with that HDMI port as defined in the Video BIOS Table (VBT).			



7.3.4 HDMI 1.4* Main Link Active Level Shifter Topology

Figure 7-4. CFL HDMI 1.4* Main Link Active Level shifter Motherboard Topology

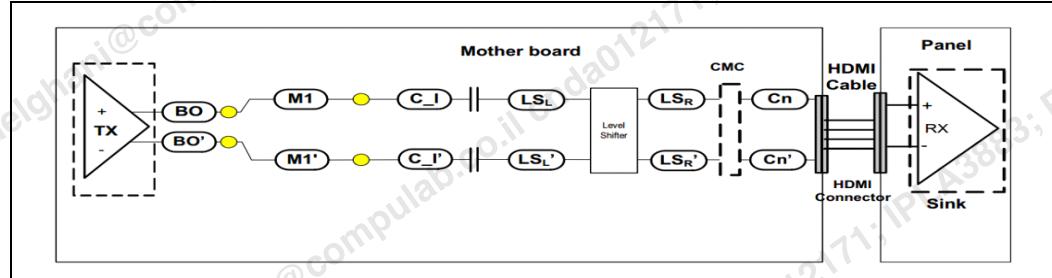
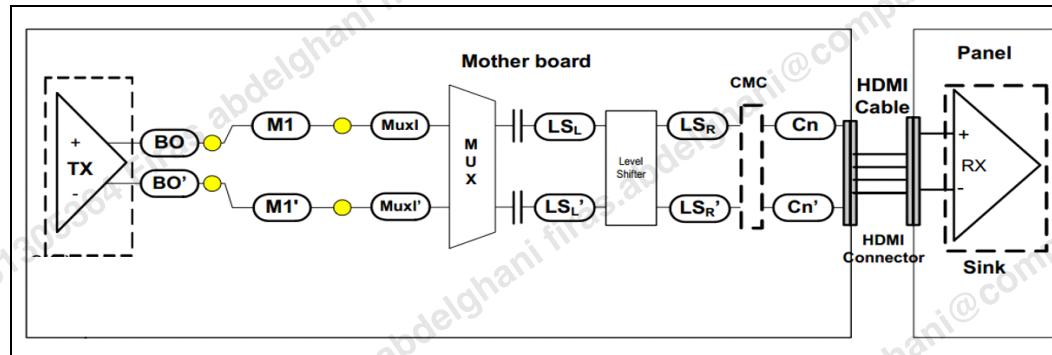


Table 7-7. CFL H HDMI 1.4* Main Link Active Level shifter Motherboard Topology Guidelines

Segment	Via Count	Stack-up	Max Length [mils]
B0	Max 3 vias are allowed	MS/SL	400
M1		MS/SL/DSL	5500
C_I		MS	5500
LSL		MS	500
M1+C_I+LSL		MS	6000
LSR+Cn		MS	1000
Total Length			6500
Notes:			
1. Topology supports Non Re-time Active Level Shifter			
2. Max 3 Vias are allowed.			
3. Must use appropriate level shifter for maximum desired data rate.			
4. ESD is recommended. CMC is optional (recommended to leave footprint on platform)			
5. Retimer Sideband Communication - Any port configured to support HDMI must implement sideband communications via the DDC (I2C) channel associated with that HDMI port as defined in the Video BIOS Table (VBT)			

Figure 7-5. CFL H HDMI 1.4* Main Link Active Level shifter Multiplexed Topology



**Table 7-8. CFL H HDMI 1.4* Main Link Active Level shifter Multiplexed Topology Guidelines**

Segment	Via Count	Stack-up	Max Length [mils]			
B0	Max 3 vias are allowed	MS/SL	500			
M1		MS/SL/DSL	6000			
Muxl		MS	500			
LSL		MS	6000			
LSR + Cn		MS	800			
Total Length		6000				
Notes:						
1. Must use appropriate level shifter for maximum desired data rate.						
2. ESD is recommended. CMC is optional (recommended to leave footprint on platform)						
3. Assumed Passive Mux						
4. Any port configured to support HDMI must implement sideband communications via the DDC (I2C) channel associated with that HDMI port as defined in the Video BIOS Table (VBT).						



7.3.5 HDMI 1.4* Docking Active Level Shifter Docking Topology

Figure 7-6. CFL H HDMI 1.4* Main Link Active Level shifter Docking Topology

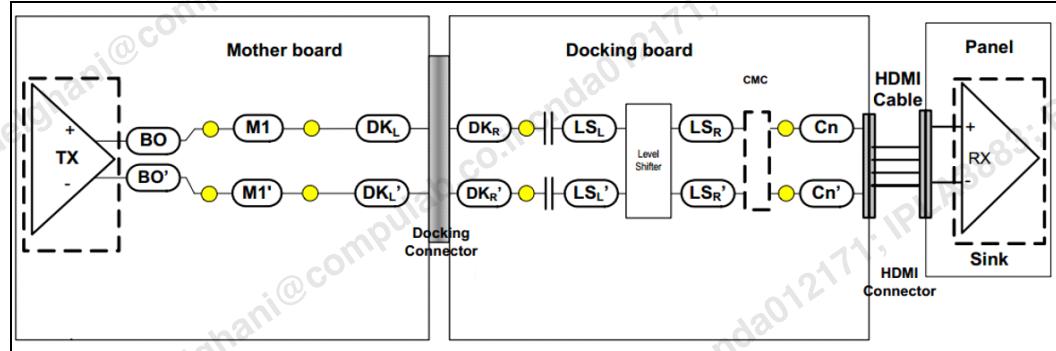


Table 7-9. CFL H HDMI 1.4* Main Link Active Level shifter Docking Topology Guidelines

Segment	Stack-up	Max Length [mils]
B0	MS/SL	400
M1	MS/SL/DSL	7100
DKL	MS	1000
DKR	MS	500
LSL	MS	2000
LSR+Cn		1000
Total Length		11000

Notes:

1. Must use appropriate level shifter for maximum desired data rate.
2. ESD is recommended. CMC is optional (recommended to leave footprint on platform)
3. Retimer Active Level Shifter.

Figure 7-7. CFL H HDMI 1.4* Main Link Active Level shifter Docking Multiplexed Topology

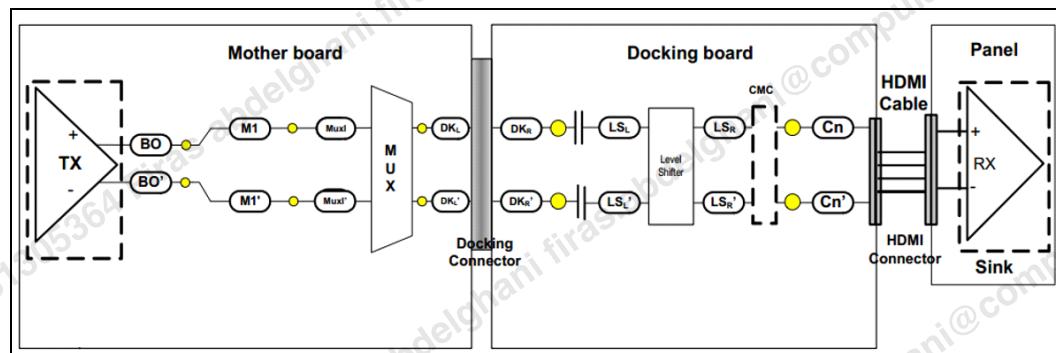


Table 7-10. CFL H HDMI 1.4* Main Link Active Level shifter Docking Multiplexed Topology Guidelines (Sheet 1 of 2)

Segment	Stack-up	Max Length [mils]
B0	MS/SL	400
M1+Muxl	MS/SL/DSL	7100

Table 7-10. CFL H HDMI 1.4* Main Link Active Level shifter Docking Multiplexed Topology Guidelines (Sheet 2 of 2)

Segment	Stack-up	Max Length [mils]
DKL	MS	1000
DKR	MS	500
LSL	MS	2000
LSr + Cn	MS	1000
Total Length		11000

Notes:

1. Must use appropriate level shifter for maximum desired data rate.
2. ESD is recommended. CMC is optional (recommended to leave footprint on platform)
3. Any port configured to support HDMI must implement sideband communications via the DDC (I2C) channel associated with that HDMI port as defined in the Video BIOS Table (VBT).
4. Docking topology assumes Re-time Active level Shifter.
5. ALS may contain integrated ESD devices not shown in the diagram
6. Retimer Active Level Shifter.

7.3.6 HDMI 1.4* Internal Cabled Solution

Figure 7-8. CFL HDMI 1.4* Internal Cabled Solution Topology

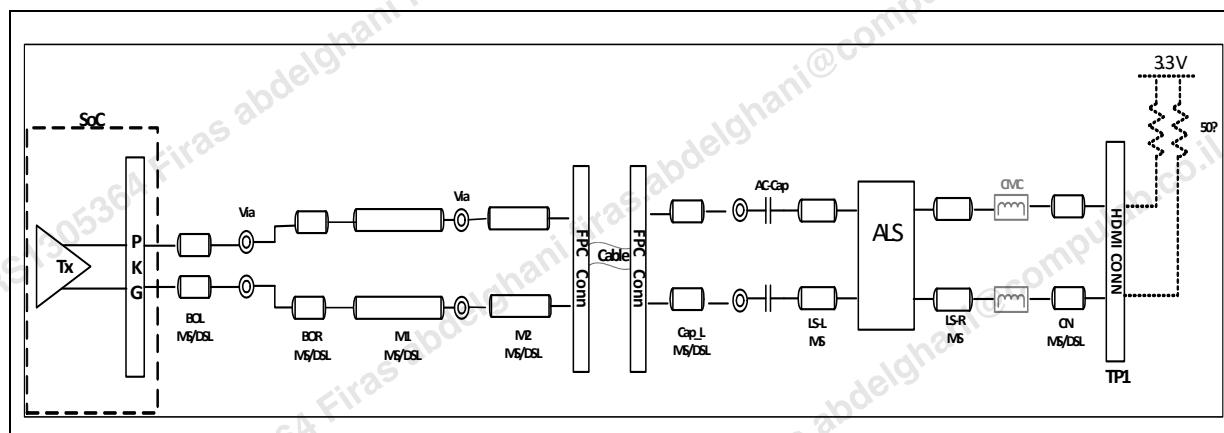


Table 7-11. CFL H HDMI 1.4* Internal Cabled Solution Topology Routing Guidelines (Sheet 1 of 2)

Segment	Via Count	Stack-up	Max Length [mils]			
Internal Cable Assembly Insertion Loss recommendation up to 1.5 GHz		dB	<=0.5	<=0.9	<=1.3	<=1.7
Reference Cable length (AWG38 100 ohm uCoax)		5000	10000	15000	20000	



Table 7-11. CFL H HDMI 1.4* Internal Cabled Solution Topology Routing Guidelines (Sheet 2 of 2)

Segment	Via Count	Stack-up	Max Length [mils]			
BOL+BOR	Max 3 vias are allowed	MS/SL	400	400	400	400
M1+M2		MS/SL/DSL	4000	3500	3000	2500
BOL+BOR+M1+M2		MS/SL/DSL	4000	3500	3000	2500
Cap_L+LS_L		MS	1000	1000	1000	1000
LS_R		MS	1000	1000	1000	1000
CN		MS	1000	1000	1000	1000
LS_R+CN		MS	1000	1000	1000	1000
Cap_L+LS_L+LS_R+CN		MS	2000	2000	2000	2000

Notes:

1. Must use appropriate level shifter for maximum desired data rate.
2. ESD is recommended. CMC is optional (recommended to leave footprint on platform)
3. Any port configured to support HDMI must implement sideband communications via the DDC (I2C) channel associated with that HDMI port as defined in the Video BIOS Table (VBT)
4. Far-end crosstalk for cable assembly is assumed to be <=-50dB up to 4.5GHz
5. Beyond the fundamental frequency (1.5GHz), the insertion loss curve is assumed to be reasonably smooth up to 4.5GHz

7.3.7

HDMI 1.4* (DDC) Signals Design Guidelines

CRTL DATA and CRTL CLK are single ended signals used for communications between the PCH, add-in card and a panel device (Sink). These two signals follow I²C specifications and HDMI DDC load (750 pF) when they operate in the standard mode of frequency of 100-kHz. Any port configured to support HDMI must implement sideband communications via the DDC channel associated with that HDMI port as defined in the Video BIOS Table (VBT). Sideband communication using I2C over AUX is not supported.

7.3.7.1

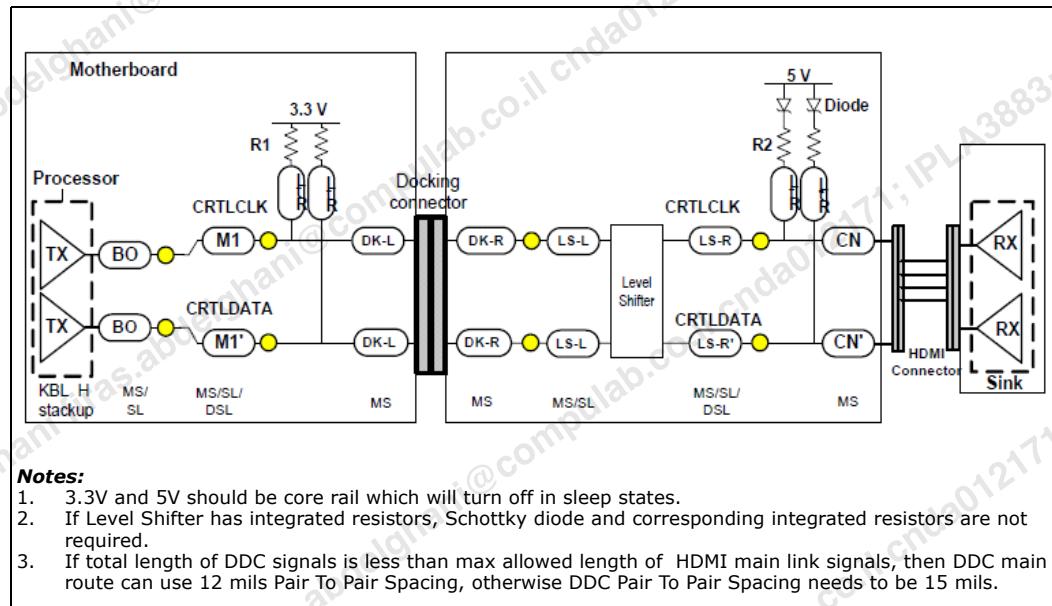
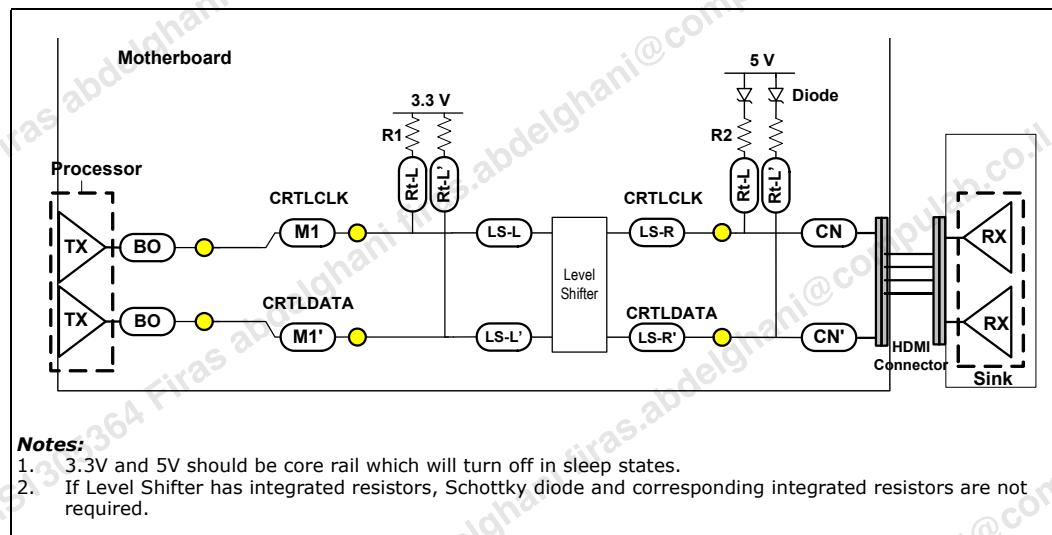
HDMI 1.4* DDC Signals on Motherboard Topologies with Cost-reduced Level Shifter, Active Level Shifter and Docking Active Level Shifter
Figure 7-9. CFL HDMI 1.4* DDC Graphics Active Level Shifter Docking Topology

Figure 7-10. CFL HDMI 1.4* DDC Graphics Active Level Shifter Topology




Figure 7-11. CFL HDMI 1.4* DDC Cost-reduced Level Shifter Design Recommendation

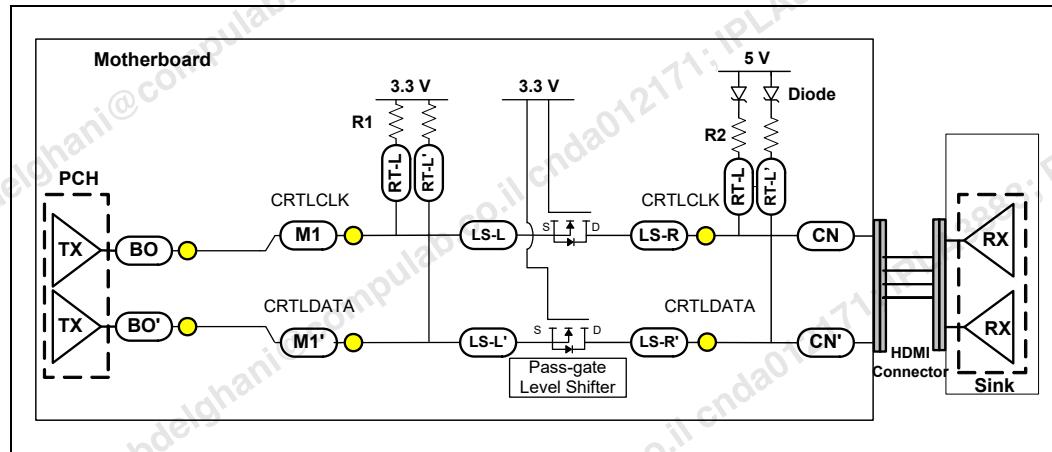


Table 7-12. CFL H HDMI 1.4* DDC Routing Guidelines (Sheet 1 of 2)

Description	Parameter	Stackup	Units	Cost Reduced Level Shifter	Active Level Shifter	Docking Active Level Shifter
				Routing Recommendations		
Coffee Lake Processor Breakout Max	BO	MS/SL/DSL	mils	500	500	500
Main Route	M1	MS/SL/DSL	mils	Constrained by Total Motherboard Length Max from Coffee Lake processor to HDMI connector		
M1 to R1	Rt-L	MS	mils	1000	1000	1000
Routing from MB to Docking connector	DK-L	MS	mils	Constrained by Total Motherboard Length Max from Coffee Lake processor to HDMI connector		
Routing on the docking connector	DK-R	MS	mils	Constrained by Total Motherboard Length Max from Coffee Lake processor to HDMI connector		
Routing to Level Shifter Length Max	LS-L	MS/SL/DSL	mils	Constrained by Total Motherboard Length Max from Coffee Lake processor to HDMI connector		
Level shifter to RT-L Length Max	LS-R	MS/SL/DSL	mils	Constrained by Total Level Shifter to HDMI connector Length Max		
RT-L to HDMI Conn Length Max	CN	MS	mils	Constrained by Total Level Shifter to HDMI connector Length Max		
Docking connector to Level Shifter Total Length max	DK-R+LS-L	MS	mils	NA	NA	500
Total Level Shifter to HDMI connector Length Max	LS-R+CN	MS	mils	1500	1500	1500
Total Motherboard Length Max	Sum (BO to CN)	Refer Topology	mils	10000	10000	10000
Passive / Active Devices						
Max Capacitance (Backdrive I Protection)	Schottky Diode	NA	pF	10	10	10
Resistor Value (+/- 5%)	R1	NA	Ω	2.2K	$2.2K^2$	$2.2K^2$
Resistor Value (+/- 5%)	R2	NA	Ω	2.2K	$2.2K^3$	$2.2K^3$

Table 7-12. CFL H HDMI 1.4* DDC Routing Guidelines (Sheet 2 of 2)

Description	Parameter	Stackup	Units	Cost Reduced Level Shifter	Active Level Shifter	Docking Active Level Shifter
				Routing Recommendations		
ESD Protection	ESD	NA	NA	Required	Assumed to be contained within level shifter	Assumed to be contained within level shifter

Notes:

1. DDC signals follow I2C guidelines. Refer to chapter 20.
2. Stuff R1 on motherboard if no equivalent internal Pull-up inside Active Level Shifter
3. Stuff R2 on motherboard if no equivalent internal Pull-up inside Active Level Shifter
4. Total length from driver to HDMI connector is limited by Spec Capacitance limit of 50pF including trace capacitance and discrete. Refer [Chapter 23, "I²C Interface Design Guidelines"](#). Refer for calculation details.
5. nFET Ron should be <3ohms and Cout < 10pF
6. ESD protection is recommended. However, if ALS chip have sufficient inbuilt ESD protection and trace length from Als to connector is <1", diodes may not be required.

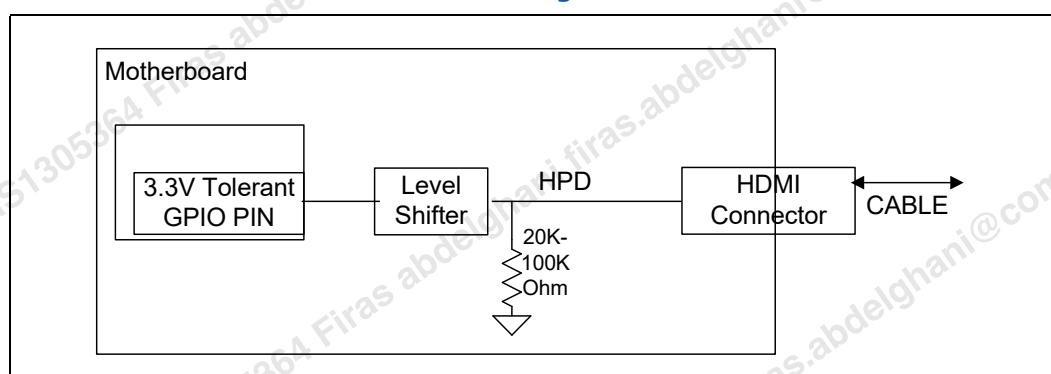
7.3.8 HDMI 1.4* HPD Implementation

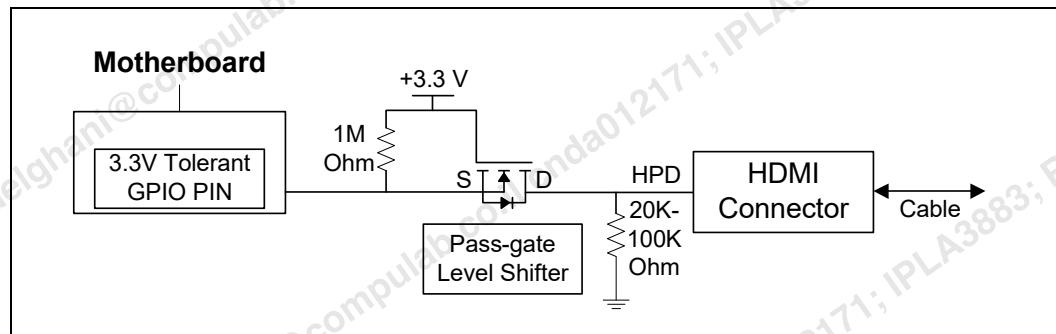
The hot-plug detect output from HDMI* sink is a 5V active high signal. The hot-plug detect input at the Coffee Lake processor is a 3.3V active high signal (refer to the EDS for DC specifications). A level shifter is required on the motherboard to convert the 5V signal from HDMI* sink device to 3.3V signals for the Coffee Lake processor. However, logic inversion is not required for this signal. Also, make sure necessary protection circuitry is in place to prevent back-drive current from damaging the Coffee Lake processor when the sink device is powered off.

Ensure HDMI* connector HPD is not directly connected to the Coffee Lake processor. Level shifter should have pass-gate circuit, if not then it is recommended to use pass-gate circuit for HPD. Refer figures below for implementation of an Active Level Shifter or a Cost Reduced Level Shifter HPD topology.

Note:

If the display connector is on the docking station, the hot-plug circuitry should remain on main motherboard and not on the docking station in order to prevent display detection failures related to hot-plug and S-state resume. HPD signal should not be allowed to float anytime.

Figure 7-12. HDMI 1.4* HPD Active Level Shifter Design Recommendation


**Figure 7-13. HDMI 1.4* HPD Cost Reduced Level Shifter Design Recommendation****Note:**

3.3V transistor gate supply must turn off when CPU power is turned off.

7.4 HDMI* 2.0 Topology Guidelines

Figure 7-14. CFL H LSPCON Main Link Direct MB Topology

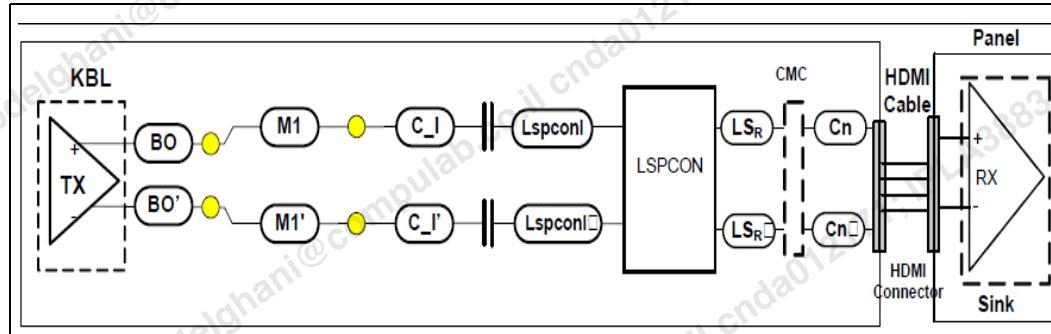


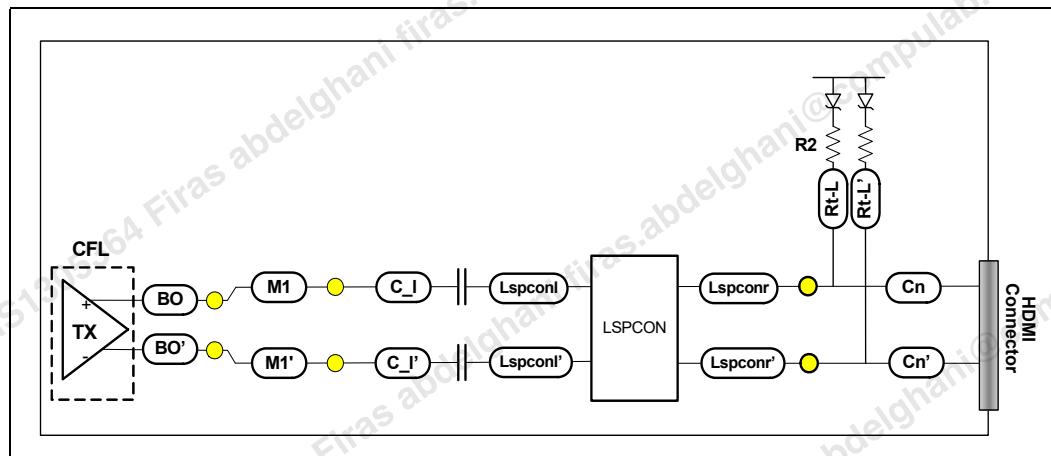
Table 7-13. CFL H LSPCON Main Link Direct MB Topology Guidelines

Segment	Via Count	Stack-up	Max Length [mils]
B0	Max 3 vias are allowed	MS	500
M1		MS	5500
M1+C_I		MS	6000
LSPCON		MS	1000
LS-R+Cn		MS	LSPCON Spec
Total Length			6500

Notes:

1. ESD should be integrated in LSPCON.
2. CMC is optional (recommended to leave footprint on platform)
3. Recommend to have reserve probing locations for LSPCON input link and testing pins.
4. reserve probing locations for LSPCON input link and testing pins.

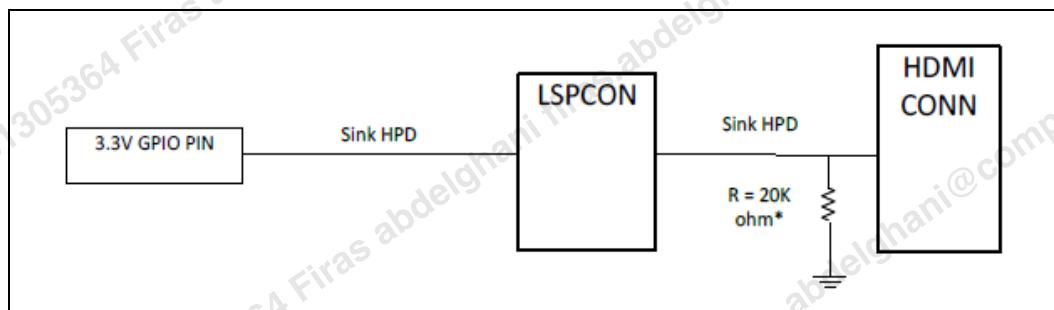
Figure 7-15. CFL H Type 3 HDMI 2.0 DDC Topology



**Table 7-14. CFL H Type 3 HDMI 2.0 DDC Topology**

Description	Parameter	CFL H	Units	CFL H LSPCON DDC
				Routing Recommendations
Coffee Lake Processor Breakout Max	BO	MS/SL/DSL	mils	500
Main Route	M1	MS/SL/DSL	mils	Constrained by Total Motherboard Length Max
Cap to LSPCON length Max	C_I+ Lspconl	MS/SL/DSL	mils	Constrained by Total Motherboard Length Max
LSPCON to via length max	Lspconr	MS/SL/DSL	mils	Constrained by Total Motherboard Length Max
Via to connector Length Max	Cn	MS	mils	Constrained by Total Motherboard Length Max
LSPCON to HDMI connector length Max	Lspconr+Cn	MS	mils	1500
Total Motherboard Length Max	Sum (BO to CN)	-	mils	13000
Passive / Active Devices				
Max Capacitance (Backdrive I Protection)	Schottky Diode	NA	pF	10
Resistor Value (+/- 5%)	R2 t	NA	Ω	2.2K*
ESD Protection	ESD	NA	NA	assumed to be contained within LSPCON
Max nFET Ron/Cout	NA	NA	Ω /pF	3 Ω /10pF
Notes:				
1. Stuff R2 on motherboard if no equivalent internal Pull-up inside Active Level Shifter.				
2. AC caps range is 75 to 200nF (nominal 100nF).				

7.4.1 HDMI 2.0* HPD Implementation

Figure 7-16. HDMI 2.0* HPD Implementation

Note:

Follow vendors' recommendation to protection against non-compliance HDMI sink which provide low impedance 5V connection to HPD pin and back drive from during off state



7.5

Digital Display Interface Disabling and Termination Guidelines

Refer to [Section 5.6, "Digital Display Interface Disabling and Termination Guidelines"](#) for HDMI* disabling and termination guidelines

7.6

Display Compensation Guidelines

Refer to [Section 5.7, "Display Compensation Guidelines"](#) for details.

Note:

There is one comp pin (eDP_RCOMP) that is shared among all display ports.

§ §



8

Processor - PCI Express* Design Guidelines

8.1 Introduction

PCI Express* is a 16-lane interface. The guidelines in the chapter cover PCI Express operation at 2.5-GT/s, 5-GT/s and 8GT/s.

8.1.1 Compliance Documents

Title	Doc #/Location
PCI Express Base Specification Rev 3.0	www.pcisig.com

8.2 Signal Description

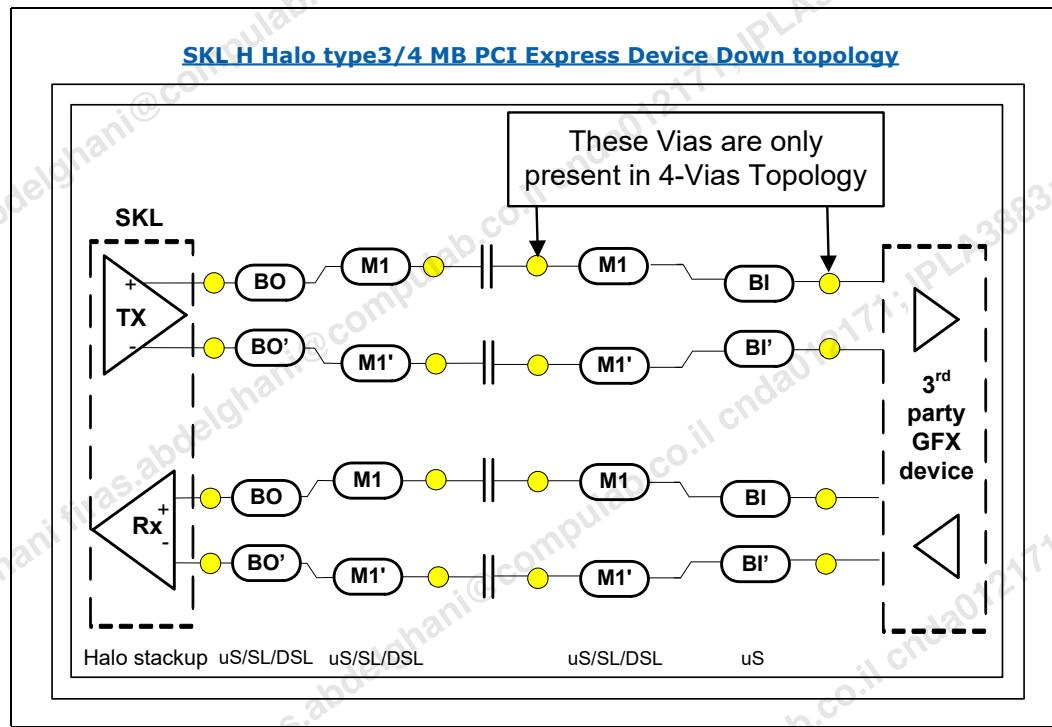
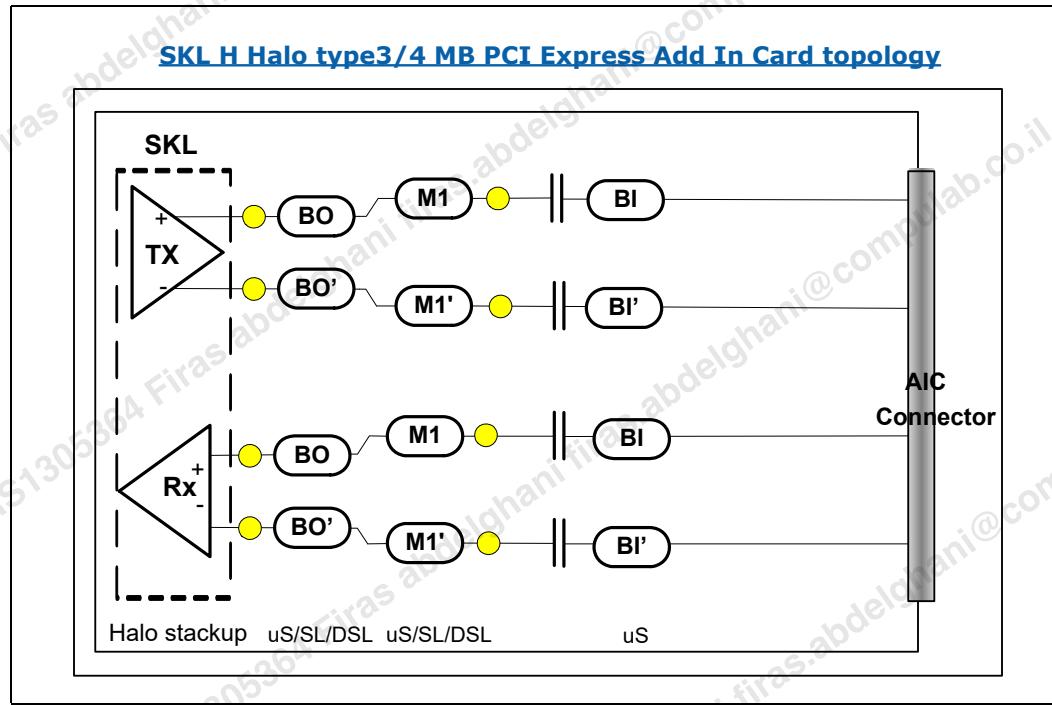
Table 8-1. PCI Express* Signal Groups

Signal Group	Signal Name	Description
Input PCI Express*	PEG_RX#[15:0] PEG_RX[15:0]	PCI Express* Receive Differential Pair
Output PCI Express*	PEG_TX#[15:0] PEG_TX[15:0]	PCI Express* Transmit Differential Pair
COMP	PEG_RCOMP	PCI Express* and DMI Compensation

8.3 Topologies Guidelines

Note:

The length difference between lanes (longest to shortest lane) within a PCIe port should not be bigger than 2".

Figure 8-1. CFL H - PCI Express® Device Down Topology

Figure 8-2. CFL H - PCI Express® Add-In Card Topology


**Table 8-2. Coffee Lake H Design Topologies (Add-In Card and Device Down)**

Description	Parameter	Stackup	Units	Halo AIC Topology	Halo Device Down (DD) Topology
				Routing	Routing
Data Rate	NA	NA	Gbps	2.5/5/8	2.5/5/8
CFL Processor Breakout	BO	uS/SL/DSL	mils	500	500
Main Route Segment Max	M1	uS/SL/DSL	mils	7000	7000
Cap to Connector	BI	uS	mils	300	300
Total Route Length	Sum BO to BI	per segment	mils	2000-7000	3000-8000 ³ / 3000-9000 ⁴
Passive Devices					
ac cap value Gen1 or Gen2	Min=75nf Max=265nf				
ac cap value Gen3	Min=180nf Max=265nf				
Notes:					
1. Halo use 12mil PTPS 2. Non Interleave route is recommended for Xtalk reduction 3. For 4 via topology 4. For 2 via topology					

Add-In Card topology assumptions:

- In the RVP topology, the add-in card is assumed to have up to 3.5 inches of max length for DT form factor designs.
- The add-in card is assumed to have up to 2.0 inches of max length for AIO form factor designs.

Add-In Card Topology Assumptions:

- The topologies in this section assume that AC-caps are placed on the platform for both Rx and Tx lanes. Such topologies are commonly required when using low-profile, horizontally mounted (with surface mounted connectors) Add-in cards, which require AC-caps to be placed on the platform.
- The recommendations detailed in this section are for a non-interleaved routed add-in card solution only, i.e., Tx and Rx lanes are routed on different layers. If different routing implemented in add-in card, simulations are required to validate interoperability. When implementing an add-in card design based on an industry specification outside of Intel, one should consult with those design specifications and recommendations to ensure an operational and interoperable design.
- The add-in card is assumed to have up to 2.0 inches of max length for AIO form factor designs.

8.4 General Routing Guidelines

8.4.1 Reference Planes

Referencing signals going over a board-to-board connector must be considered and stitching capacitors added at the connector as appropriate. For example, if a differential-pair is GND-referenced on the motherboard and the pair is V_{CC} referenced on the daughter card, then stitching capacitors must be added at the connector between V_{CC} and GND.

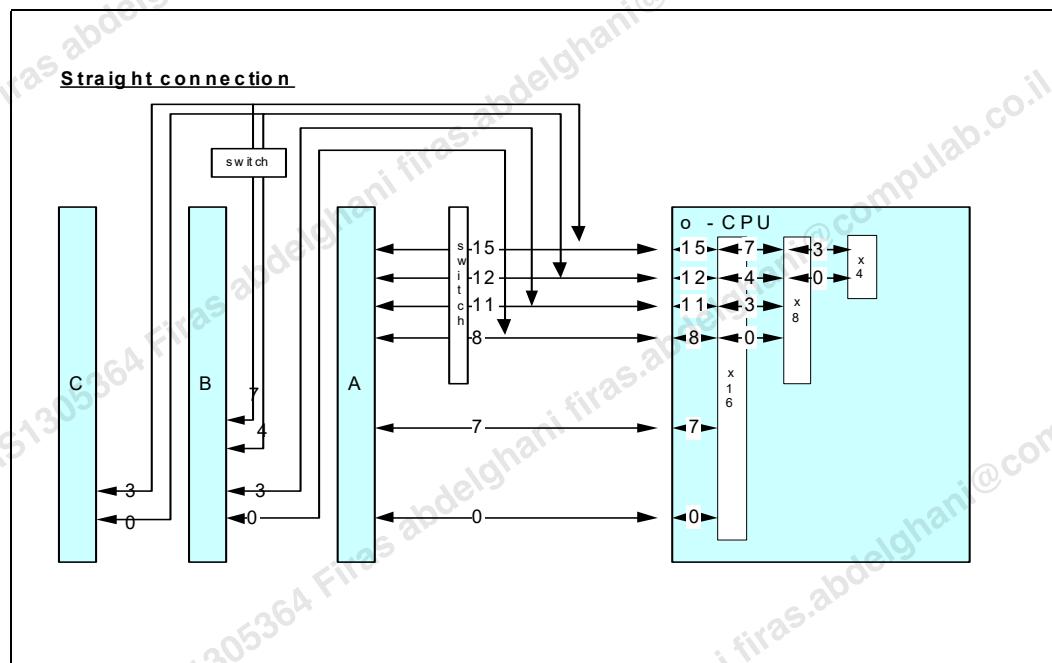
8.4.2 Lane to Controller Allocation

The PCI Express has 16 physical lanes that can be configured in several ways, it can be configured by a single controller as a 16-lane interface, or with two controllers to form a two 8-lane interfaces. It can be configured to be 1 x 8 lane and 2 x 4 lanes interfaces with three controllers. These types of configurations are determined statically by BIOS prior to initialization of the port(s). BIOS may look at card "presence detect" pins to change this setting.

The 16 lanes are associated with root port of device 1
Function 0 refers to the controller of the x16
Function 1 refers to the controller of the x8
Function 2 refers to the controller of the x4

Figure 8-3 shows the x16 lanes port split for the three controller connection to the physical lanes. Note that the external switches in the diagram may not be possible in GEN2 and GEN3 rates.

Figure 8-3. x16 Lanes Port Splitting



8.4.2.1 Static Lane Reversal Support

The Processor has two strap pins that will be driven by card detect of port B and C. This will allow the platform to enable the second and third controllers and control the external switches for GEN 1 rates. The root port supports static lane reversal. BIOS reference code may not fully support preset search algorithm on systems with lane reversal on PCIe ports. BIOS will fully support GEN 3 by use of presets programmed at customer discretion with Intel guidance. The target for the lane reversal support is to ease mother board layout. Card layout is not supported and should be handled by downstream device.

For the shared 16 lanes only one reversal option is supported regardless of the port split. This allows to design motherboard with straight or rotated processor relative to the PCI Express® slots or to rotate all the slots together. There is no support for different slots having different orientation.

Figure 8-4. Card Presence Detect Pin Connections

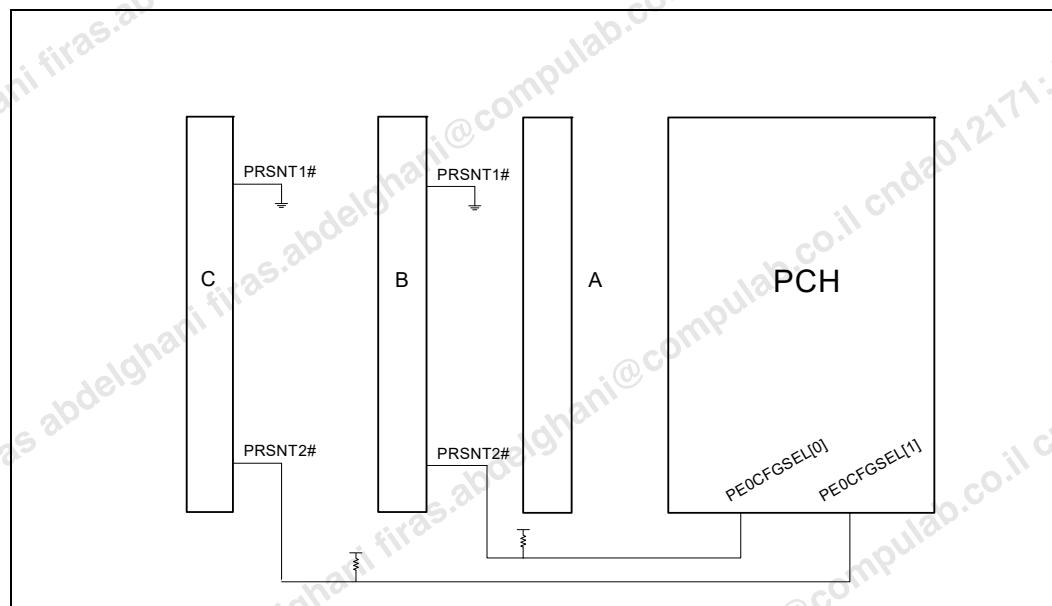


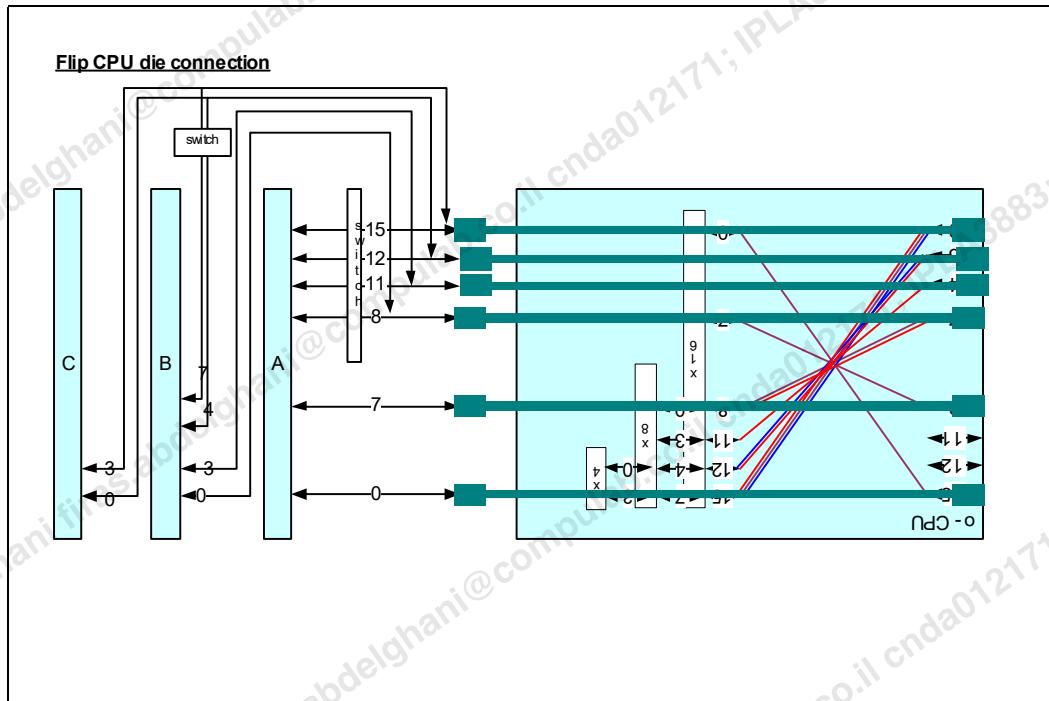
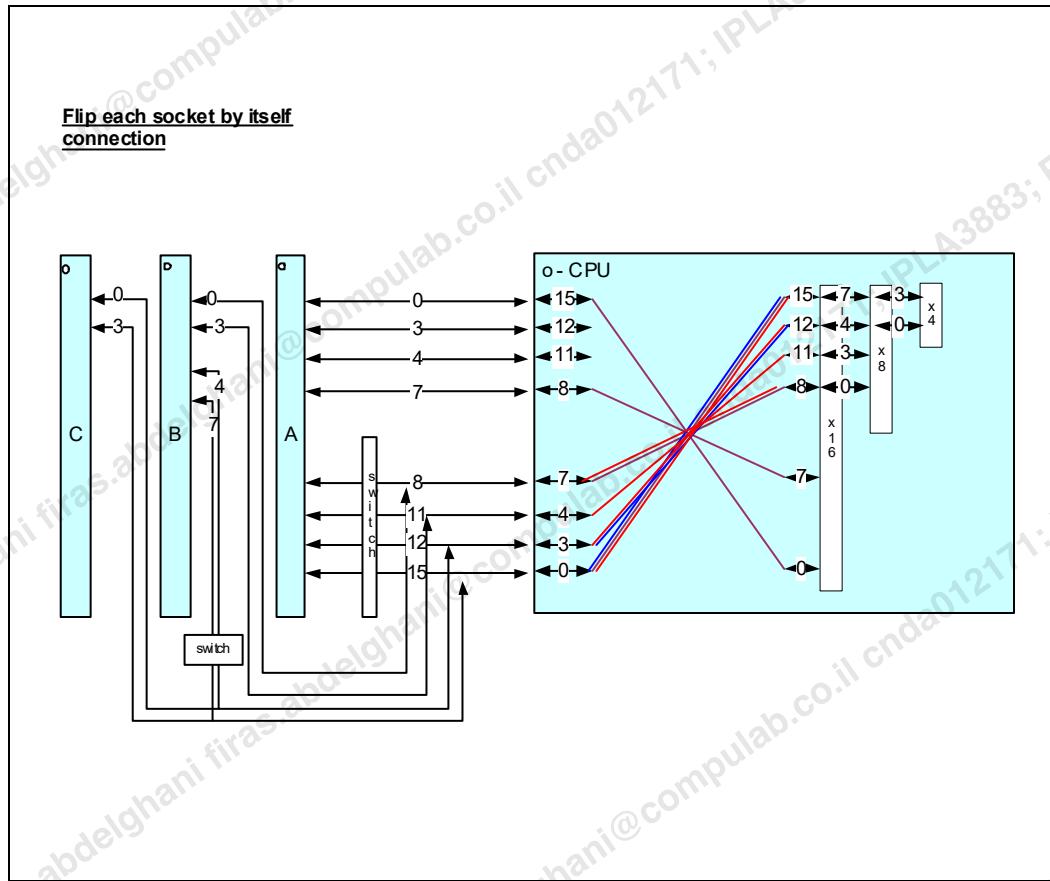
Figure 8-5. x16 Configuration with Flipped Processor

Figure 8-5 shows the configuration on how to connect the x16 lanes with a flipped processor die connection.

Figure 8-6. x16 Configuration with Flipped Socket

**Table 8-3. Few Supported Normal and Lane-reversed Bifurcation Configurations**

x16 Controller Negotiated Width	x8 Controller Negotiated Width	x4 Controller Negotiated Width	Processor	Physical Lanes															
				0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
x16	Off	Off	Direct	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
x8	x8	Off	Direct	0	1	2	3	4	5	6	7	0	1	2	3	4	5	6	7
x8	x4	x4	Direct	0	1	2	3	4	5	6	7	0	1	2	3	0	1	2	3
x16	Off	Off	Reverse	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
x8	x8	Off	Reverse	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
x8	x4	x4	Reverse	3	2	1	0	3	2	1	0	7	6	5	4	3	2	1	0

Notes:

1. Support is also provided for narrow width and use devices with lower number of lanes (that is, usage on x4 configuration), however further bifurcation is not supported.
2. In case that more than one device is connected, the device with the highest lane count, should always be connected to the lower lanes, as follows:
 - Connect lane 0 of 1st device to lane 0.
 - Connect lane 0 of 2nd device to lane 8.
 - Connect lane 0 of 3rd device to lane 12.For example:
 - a. When using 1x8 + 2x4, the 8 lane device must use lanes 0:7.
 - b. When using 1x4 + 1x2, the 4 lane device must use lanes 0:3, and other 2 lanes device must use lanes 8:9.
 - c. When using 1x4 + 1x2 + 1x1, 4 lane device must use lanes 0:3, two lane device must use lanes 8:9, one lane device must use lane12.

Table 8-4. PCIe* Configurations

Configuration	PCIe Slot Clock
1x16	Customer can use any of the available clock out signals. For example CLKOUT_PCIE_8 was used on RVP.
2x8	Customer can use any of the two available clock signals. For example CLKOUT_PCIE_10 and CLKOUT_PCIE_14
1x8+2x4	Customer can use any of the three available clock signals. For example CLKOUT_PCIE_11, CLKOUT_PCIE_12 and CLKOUT_PCIE_13

8.5 Slot Reset Implementation

AND gate implementation (with inputs –PLTRST# and PCH GPP_F22) should be used for resetting PEG slots. This circuit provides an option to reset PEG slots using BIOS-controlled GPP_F22 during debug, without resetting the entire platform.

A jumper should be added near the PEG slots to select between the PLTRST# directly OR the ANDed output of PLTRST# and GPP_F22. GPP_F22 should follow same routing guidelines as platform reset.

The BIOS needs to ensure that GPP_F22 is configured as output high for normal operation. This circuit will take effect and reset PEG slots only when GPP_F22 is driven low.

PCIe Gen3 margining and functional link training can occasionally hang PEG devices (slots or down). To ensure proper system functionality, Intel recommends implementing a circuit that allows the BIOS to reset the PEG device, independent of PLTRST#. The reference circuit on the Coffee Lake H RVP uses GPP_F22 to control the

auxiliary reset circuit, but the BIOS Reference Code allows a different GPIO to be used, if necessary for the system design flexibility. Unless necessary, customers are advised to use the default GPIO selection. Equivalent reset circuits are also acceptable. The auxiliary reset circuit is only required for PCIe Gen3 implementations.

8.6 Debug Guidelines

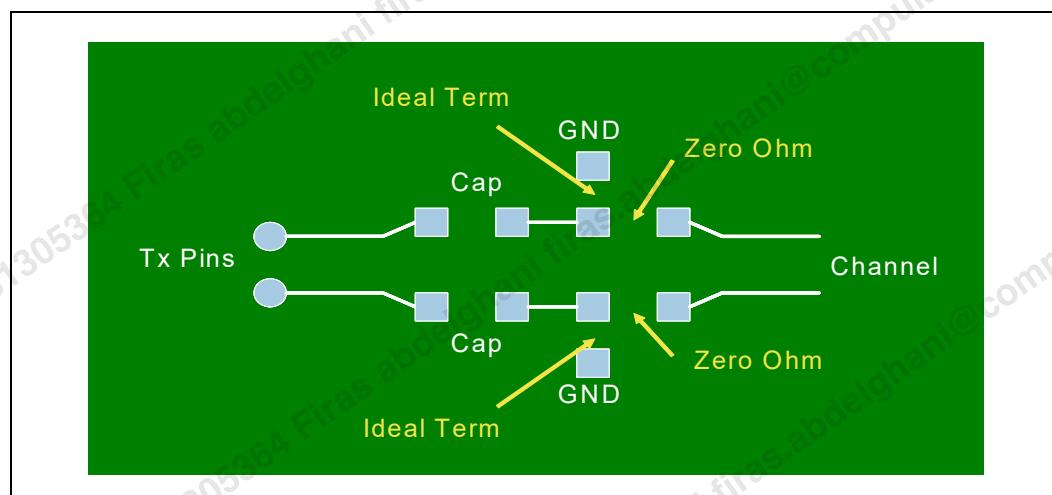
The inclusion of test points and probing structures may impact the loss and jitter budgets of a PCI Express interconnect. In general, test points and probe structures should not introduce stubs on the differential pairs or cause significant deviation from the recommendations given throughout this chapter. Existing vias, pads or pins should be used wherever possible to accommodate such structures. Careful consideration must be taken whenever additional probing structures are used.

8.6.1 Probe Points for Testing Soldered Down PCI Express® Devices

In order to actively characterize the transmit path signal quality for a soldered down PCI Express® device, there must be a terminated probing point on the motherboard very near the soldered down device. This probing point may affect the overall signal quality of the system during normal operation due to the effects of stubs and impedance mismatches of the traces themselves.

The probing point requires populating a resistor stuffing option that can be used to break the path to the device very near the device pins and ideally terminate each line (TX+/TX-) to ground through a $50\ \Omega$ 1% resistor. Also, an AC coupling capacitor is required near the device pins. The resistor package/footprint must be as small as possible, preferably size 0402. The population of a $50\text{-}\Omega$ resistor, as shown in Figure 8-7, will force the transmitting silicon (host or add-in card) to enter the compliance mode and begin transmitting the compliance packet. The population of two $0\text{-}\Omega$ resistors will allow normal operation of the device. One replace the AC coupling cap, the other connects the channel.

Figure 8-7. Board Preparation Example





8.6.2 Desktop Form Factor Passive Components and Connectors

8.6.2.1 Desktop Form Factor AC Coupling Capacitor Placement Guidelines

The *PCI Express® Specification* requires that each lane of a PCI Express® link be AC coupled between the driver and receiver. The specification allows for the actual AC coupling capacitors to be located either on or off the die. However, it is anticipated that in most cases the AC coupling will be separate from the die and in the form of discrete capacitors on the PCB board itself. Use the following guidelines for AC coupling capacitors:

- For add-in cards, the AC coupling capacitors are located on the card itself for each of the TX pairs originating from the add-in card PCI Express® device and going to a RX pair on the motherboard. For the motherboard, the AC coupling capacitors are required on the motherboard itself for the TX pairs originating from the motherboard PCI Express® device and going to the add-in card's RX pairs.
- Dielectric properties are not a major consideration for PCI Express® AC coupling capacitors. It is anticipated that any type from COG capacitors to X7R is acceptable as long as the capacitors meet all other requirements.

Table 8-5. Desktop Form Factor AC Coupling Capacitor Guidelines

Parameter (For AC Coupling Capacitors)	Requirement
Cap size	<ul style="list-style-type: none">• 0402• C-packs are not allowed
Cap Value	<ul style="list-style-type: none">• 180 nF min• 265 nF max• Cap values must be the same for each signal in a differential pair• Recommend using a nominal Cap Value of 220 nF
Cap Value Tolerance	<ul style="list-style-type: none">• Not applicable as long as specified min/max range is met when the tolerance is considered.
Cap Placement—Coupled Pair	<ul style="list-style-type: none">• Must be placed at same exact location within the two signal lines• Symmetric routing into the caps and matched line lengths on either side of the caps for each line of the diff pair.

Each lane of a PCI Express link must be AC coupled between the driver and receiver. The PCIe specification allows for the AC coupling capacitors to be located either on or off the die. However, in most cases the AC coupling is separated from the die and is in the form of discrete capacitors on the motherboard. Use the following guidelines for AC coupling capacitors.

For Tx pairs originating from the processor, and going to the add-in card Rx pairs, the AC coupling capacitors are located on the motherboard.

For newer low profile graphic cards, which require the AC coupling capacitors be placed on the motherboard, the AC coupling capacitors must be placed on the motherboard for Tx pairs originating from the AIC PCI Express device and going to Rx pairs on the motherboard.



8.6.2.2 Desktop Form Factor Connectors

The *PCI Express® Card Electro-Mechanical Specification* defines the connector to use in conjunction with edge finger add-in cards. However, several items worth mentioning with respect to the connector are listed below:

- For through-hole connectors, the pins of a differential pair are offset from each other. This delta of mismatch between the pins should be directly accounted for by the PCB trace on the system board. Refer to the Length Matching section of this chapter for more details on length matching requirements.
- The two traces of a differential pair should both route into a connector pin field from the same layer.
- The connectors and the add-in cards are keyed such that smaller cards can be put in larger connectors. For example, an x1 card can be inserted into the x4, x8, and x16 connectors. This is referred to as up-plugging. No known layout adjustments need to be made in order to accommodate up-plugging.

8.6.3 AIO Form Factor Passive Components and Connectors

8.6.3.1 AIO Form Factor AC Coupling Capacitor Placement Guidelines

Adjacent differential pairs on the connector are separated by two ground pins to manage the connector crosstalk. Ground pins should directly tie to the ground plane on the system board.

Each lane of a PCI Express link must be AC coupled between the driver and receiver. The PCIe specification allows for the AC coupling capacitors to be located either on or off the die. However, in most cases the AC coupling is separated from the die and is in the form of discrete capacitors on the motherboard. Use the following guidelines for AC coupling capacitors.

For Tx pairs originating from the processor, and going to the add-in card Rx pairs, the AC coupling capacitors are located on the motherboard.

For newer low profile graphic cards, which require the AC coupling capacitors be placed on the motherboard, the AC coupling capacitors must be placed on the motherboard for Tx pairs originating from the AIC PCI Express device and going to Rx pairs on the motherboard.

Table 8-6. AIO Form Factor AC Coupling Capacitor Guidelines (Sheet 1 of 2)

Parameter	Recommendation
Cap size	<ul style="list-style-type: none"> • 0402 strongly encouraged ⁽¹⁾ • C-packs are not allowed ⁽²⁾
Cap Value ⁽³⁾	<ul style="list-style-type: none"> • 180 nF min • 265 nF max • Recommend using a nominal Cap Value of 220 nF • Cap values must be the same for each signal in a differential pair • Cap values do not need to be matched among different differential pairs.

**Table 8-6. AIO Form Factor AC Coupling Capacitor Guidelines (Sheet 2 of 2)**

Parameter	Recommendation
Cap Placement — within a pair	<ul style="list-style-type: none">Place caps at the same linear location along the signals of a given differential-pair.The breakout into and out of the capacitors should be symmetrical for both signal lines in a differential-pair.⁽⁵⁾For each differential pair, place the capacitors as close to each other as possible per DFM rules.
Cap Separation – within a pair	<ul style="list-style-type: none">Place the capacitors as close to each other as possible per DFM rules for size 0402 caps.
Cap Placement - pair-to-pair	<ul style="list-style-type: none">No requirements to length match the routing from the processor to AC coupling caps among the differential pairs.

Notes:

- While the size 0603 capacitors are acceptable, size 0402 capacitors are strongly encouraged since the smaller package size reduces the series inductance and smaller package size reduces the overall board area needed to place the capacitors. Customers are encouraged to use smaller package size if available for example 0201.
- C-packs are not recommended for PCI Express AC coupling capacitor. VNA measurements have shown that the loss across the channel due to crosstalk is significant and causes a severe decrease in margin. Also, layout studies show only a small decrease in board area for the placement of the 0504, x2, C-packs compared with 0402 discrete capacitors (less than 10%).
- Capacitance value tolerance is not applicable as long as specified min/max range is met when the tolerance is taken into account.
- Routing studies have shown that the AC coupling capacitors can be placed in less than 0.3-square inch (194-square mm). This placement strategy completely utilizes the routing channels in between processor and the graphics controller.
- The breakout into and out of the capacitors should be symmetrical for both signal lines in a differential-pair. Minimize this trace route to maximize the amount of coupling between the signals within the pair; this helps minimize the common mode noise introduced.

8.6.3.2 AIO Form Factor Connectors

Adjacent differential pairs on the connector are separated by ground pins to manage the connector crosstalk. Ground pins should directly tie to the ground plane on the system board.

The topologies in this section assume that AC-caps are placed on the platform for both Rx and Tx lanes. Such topologies are commonly required when using low-profile, horizontally mounted (with surface mounted connectors) Add-in cards, which require AC-caps to be placed on the platform.

8.6.4 Passive Components

Table 8-7. AC Coupling Capacitor Guidelines (Sheet 1 of 2)

Parameter (For AC Coupling Capacitors)	Requirement
Cap size	<ul style="list-style-type: none">0402C-packs are not allowed
Cap Value	<ul style="list-style-type: none">180 nF min265 nF maxCap values must be the same for each signal in a differential pairRecommend using a nominal Cap Value of 220 nF
Cap Value Tolerance	<ul style="list-style-type: none">Not applicable as long as specified min/max range is met when the tolerance is considered.

**Table 8-7. AC Coupling Capacitor Guidelines (Sheet 2 of 2)**

Parameter (For AC Coupling Capacitors)	Requirement
Cap Placement—Coupled Pair	<ul style="list-style-type: none"> Must be placed at same exact location within the two signal lines Symmetric routing into the caps and matched line lengths on either side of the caps for each line of the diff pair.
Cap Location—Chip to Connector Routing	<ul style="list-style-type: none"> Capacitors should be generally placed within 450 mils of the connector no matter what the configuration is i.e. (x16, x8, x4, x2, x1) or form factor.

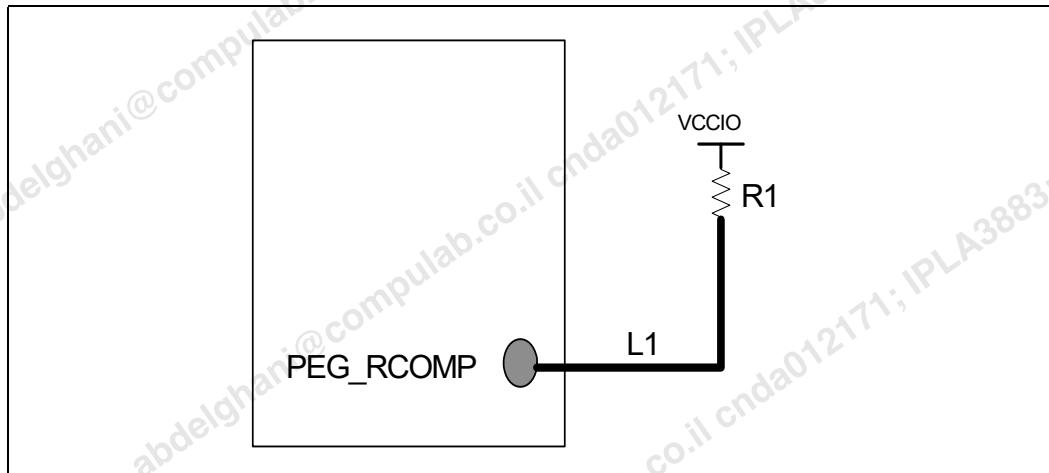
Each lane of a PCI Express link must be AC coupled between the driver and receiver. The PCIe specification allows for the AC coupling capacitors to be located either on or off the die. However, in most cases the AC coupling is separated from the die and is in the form of discrete capacitors on the motherboard. Use the following guidelines for AC coupling capacitors.

Table 8-8. AC Coupling Capacitor Guidelines

Description	Recommendation
Intra pair Placement Mismatch	Max = 5 mil
Intra pair Cap Separation	DFM minimum for size 0402 capacitors
Pair-to-Pair Cap Matching	Not required
Notes:	
<ol style="list-style-type: none"> Locate capacitors at the same linear location along the signals of a given differential-pair. No more than a 5-mil (0.127-mm) delta should exist between the differential signals on the trace segments on either side of the AC coupling capacitor. There is no requirement to length match the routing from processor to the AC coupling capacitors between the differential-pairs. Place the capacitors as close to each other as possible per DFM rules for each differential pair. While the size 0603 capacitors are acceptable, size 0402 capacitors are strongly encouraged since the smaller package size reduces the series inductance and smaller package size reduces the overall board area needed to place the capacitors. Customers are encouraged to use smaller package size if available for example 0201. Pad sizes for each of the capacitors should be the minimum allowed per DFM to minimize parasitics. The same capacitor package size should be used for each signal in a differential-pair. C-packs are not recommended for PCI Express AC coupling capacitor. VNA measurements have shown that the loss across the channel due to crosstalk is significant and causes a severe decrease in margin. Also, layout studies show only a small decrease in board area for the placement of the 0504, x2, C-packs compared with 0402 discrete capacitors (less than 10%). The breakout into and out of the capacitors should be symmetrical for both signal lines in a differential-pair. Minimize this trace route to maximize the amount of coupling between the signals within the pair; this helps minimize the common mode noise introduced. Routing studies have shown that the AC coupling capacitors can be placed in less than 0.3-square inch (194-square mm). This placement strategy completely utilizes the routing channels in between processor and the graphics controller. 	

8.7 Compensation Guidelines

The signal PEG_RCOMP should be connected to the VCCIO via a single $24.9 \Omega \pm 1\%$ resistor. Refer to the figure below for details on routing.

Figure 8-8. Processor PCI Express Compensation Signal Routing Topology

Table 8-9. Processor PCI Express* Compensation Signal Routing Guidelines

Parameter	Segment	Units	Min Trace Width	Trace Spacing to Other Signals	Max Routing Length	Resistance
PEG_RCOMP ¹	L1	mils	5	15	600	NA
Resistor	R1	Ω	NA	NA	NA	$24.9 \pm 1\%$

Note: Must maintain low DC resistance routing ($<0.1 \Omega$)

§§



9 Direct Media Interface Design Guidelines

9.1 Introduction

Direct Media Interface (DMI) connects the Coffee Lake Processor and PCH components via a high-bandwidth bus and maintains a low pin count.

9.1.1 Compliance Specification

Title	Location
<i>PCI Express Base Specification</i>	http://www.pci.org

9.2 Signal Descriptions

Table 9-1. DMI Signal Groups

Signal Name	Description
DMI_TXN[3:0], DMI_TXP[3:0] DMI_RXN[3:0], DMI_RXP[3:0]	DMI Receive/Transmit Differential Pair
PEG_RCOMP	Processor DMI compensation Signal

9.3 Topology Guidelines

DMI interface is composed of eight differential signal pairs or four lanes. Trace lengths greatly impact the loss and jitter budgets of the interconnect and the resulting bus margin. Variations in these design rules are possible, but require simulation to ensure compliance is maintained. Avoid routing Legacy signals adjacent to DMI high-speed differential signals.

9.3.1 Differential-Pair Width and Spacing

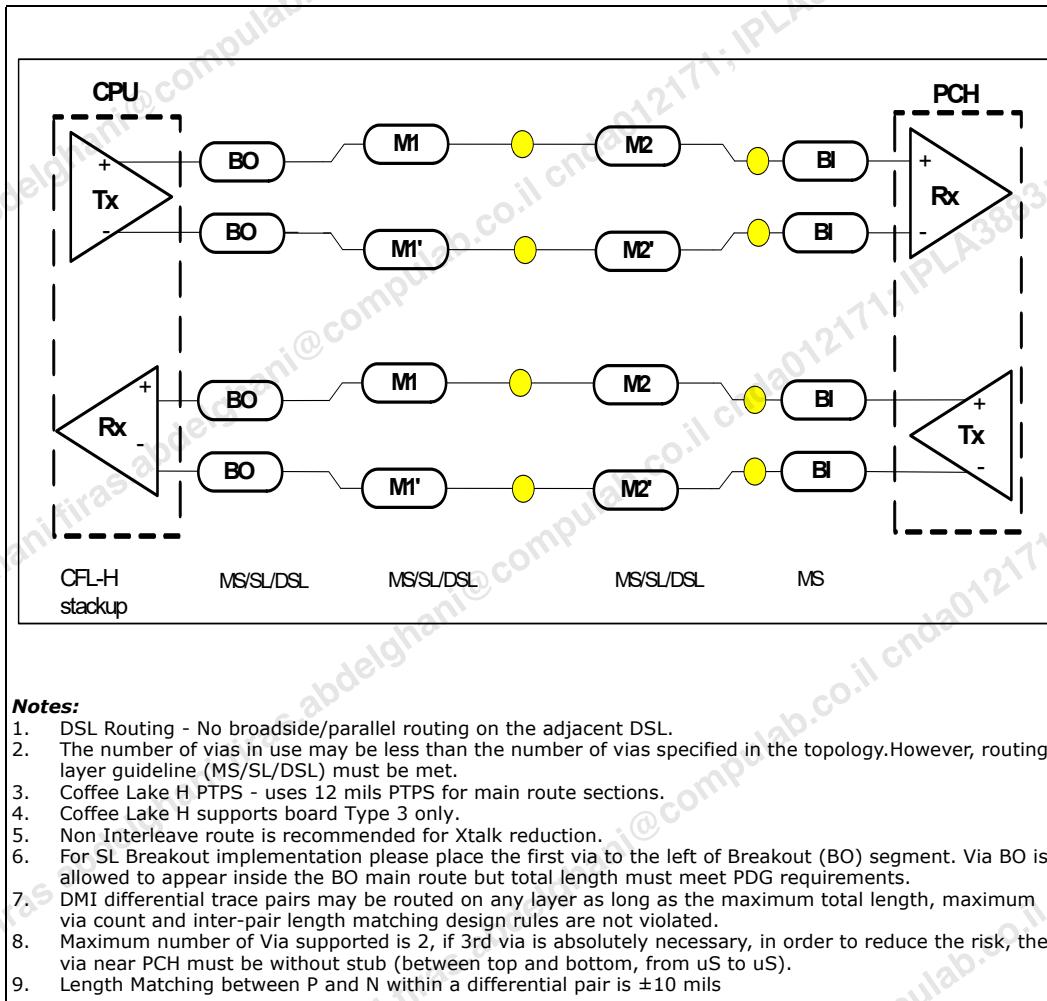
DMI supports MS/SL/DSL. Follow the guidelines in "Printed Circuit Board (PCB) Considerations".

9.3.2 DMI 2-Via Topology

Note: DMI differential trace pairs may be routed on any layer as long as the max total length, max via count, inter-pair length matching design rules are not violated.

Note: The length difference between lanes (longest to shortest lane) within a DMI port should not be bigger than 2"

DM

Figure 9-1. DMI 2-Via Topology

Table 9-2. DMI 2-Via Topology Routing Guidelines (Sheet 1 of 2)

Description	Parameter	Stackup		Routing Topology		Units
		Coffee Lake S DT Tower	Coffee Lake S DT AIO	Coffee Lake S DT Tower	Coffee Lake S DT AIO	
Data Rate	N/A	N/A	N/A	8	8	Gbps
CFL Processor Breakout	BO	MS	MS/SL/DSL	300	300	mils
Main Route Segment Max	M1	MS	MS/SL/DSL	1500	1500	mils
Main Route Segment Max	M2	MS	MS/SL/DSL	7000	7000	mils
Route on MB (Mux left)	BI	MS	MS	300	300	mils
Total Route Length Min-Max ^{3, 4}	Sum BO to BI	per segment	per segment	1000-7000	1000-7000	mils

**Table 9-2. DMI 2-Via Topology Routing Guidelines (Sheet 2 of 2)**

Description	Parameter	Stackup		Routing Topology		Units
		Coffee Lake S DT Tower	Coffee Lake S DT AIO	Coffee Lake S DT Tower	Coffee Lake S DT AIO	
Notes:						
1.	Differential-Pair length matching should be maintained segment-to-segment.					
2.	Non - Interleaved routing is recommended.					
3.	Total Length Min-Max limit requirements should not be violated.					

9.4 Configuration

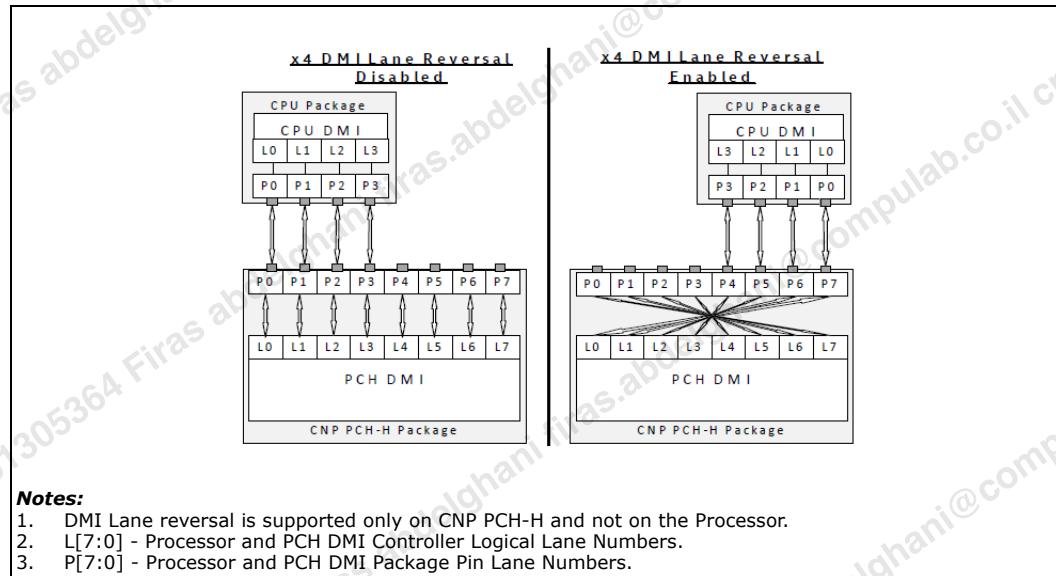
9.4.1 Lane Reversal and Polarity Inversion Support

Lane Reversal is only supported in PCH DMI Link. OEM can enable this feature in PCH to ease the DMI Link routing (between CPU and PCH) on the board. PCH DMI Lane Reversal is enabled or disabled through SoftStrap.

Polarity inversion is supported on all the Receiver Lanes in PCH DM. PCH DMI will autonomously detects the polarity inversion (Rxp and Rxn is connected reversed) based on the Training Sequence received and enabled it during Link Training.

Note:

For more information refer Processor and PCH EDS Vol.1

Figure 9-2. DMI Lane Reversal Example

**9.5****Compensation Guidelines**

Resistance Compensation for DMI is same for PEG. Refer to PEG chapter for the guidelines.

§ §



10 Hybrid Graphics

10.1 Introduction

Microsoft* Hybrid Graphics definition includes the following:

- The system contains a single integrated GPU and a single discrete GPU.
- It is a design assumption that the discrete GPU has a significantly higher performance than the integrated GPU.
- Both GPUs shall be physically enclosed as part of the system.
 - MS Hybrid DOES NOT support hot-plugging of GPUs
 - OEMS should seek further guidance from MS before designing systems with the concept of hot-plugging
- Starting with Th1 (WDDM 2.0), a previous restriction that the discrete GPU is a render-only device, with no displays connected to it, has been removed. A render-only configuration with NO outputs is still allowed, just NOT required.

It must be noted that systems that have outputs available off of the discrete GPU will NOT support previous versions of the OS (Windows 8.1 and Older).

Microsoft Windows 10 operating system enables the Win10 Hybrid graphics framework wherein the GPUs and their drivers can be simultaneously utilized to provide users with the benefits of both performance capability of discrete GPU (dGPU) and low-power display capability of the processor GPU (iGPU). For instance, when there is a high-end 3D gaming workload in progress, the dGPU will process and render the game frames using its graphics performance, while iGPU continues to perform the display operations by compositing the frames rendered by dGPU.

Each vendor [Intel as the vendor of integrated GPU / 3rd Party Graphics Vendor / Microsoft] is responsible for their own component, and Microsoft owns the overall implementation including all Hybrid Graphics related documentation and guidance.

Hybrid Graphics has requirements which determine support on different platforms and these requirements may be different between versions of OS. See Microsoft documentation for detailed requirements per OS version.

The iGPU device is configured as the primary display adapter driving the embedded or local flat panel of the device. If dGPU is designated to drive the internal display, it gets configured as primary display adapter. In this scenario, and when there is no external display driven by iGPU, the system ceases to qualify as a hybrid graphics, and it rather behaves like any discrete graphics system where the capabilities of iGPU is not utilized.

Having a system configured where both iGPU and dGPU are driving displays needs to be carefully evaluated especially if there is difference in display capabilities of the two graphics adapters that would lead to user confusion or bad UX.

§ §



11 Thunderbolt™ Design Guidelines

Thunderbolt™ technology (TBT) is a transformational high-speed, dual protocol I/O, and it provides flexibility and simplicity by encapsulating both data (PCIe*) and video (DisplayPort*) on a single cable connection that can daisy-chain up to six devices.

Alpine/Titan Ridge are Thunderbolt controllers that acts as a point of entry or a point of exit in the Thunderbolt domain. The Thunderbolt domain is built as a daisy chain of Thunderbolt enabled products for the encapsulated protocols - PCIe and DisplayPort. These protocols are encapsulated into the Thunderbolt fabric and can be tunneled across the Thunderbolt domain. Alpine/Titan Ridge Thunderbolt controller also acts as a flexible re-driver for DP protocol and a source for xHCI controller.

Alpine/Titan Ridge can be implemented in various systems such as PCs, laptops and tablets, or devices such as storage, docks, displays, home entertainment, cameras, computer peripherals, high end video editing systems, and any other PCIe based device that can be used to extend system capabilities outside of the system's box.

Alpine/Titan Ridge Thunderbolt connection data rate is 20Gbps per lane and is compatible with Thunderbolt 3 specification enabling a Thunderbolt link at up to 2x20Gbps, as well as backward compatible with Thunderbolt 1 (10Gbps) and Thunderbolt 2 (2x10Gbps) specifications.

Alpine/Titan Ridge port connectivity is through USB Type-C connector supporting the following modes:

Connection Type	Mode	USB-C Port Details
USB	Native	Single SSP/SS + Single HS/FS/LS USB connection
Thunderbolt	Alternate	Dual Thunderbolt lanes running at 10Gbps/20Gbps
Display Port	Alternate	x1/x2/x4 Display Port running at 1.62Gbps/2.7Gbps/5.4Gbps/ 8.1Gbps ¹ signaling rate
Multi Function Mode	Alternate	Single SSP/SS + Single HS/FS/LS USB connection + x2 Display Port running at 1.62Gbps/2.7Gbps/5.4Gbps/8.1Gbps ¹ signaling rate
Note: 1. 8.1Gbps is only supported on Titan Ridge		

Table 11-1. Acronyms

Acronyms	Description
TBT	Thunderbolt™ Technology
SSP	Super Speed Plus
SP	Super Speed
AR	Alpine Ridge
TR	Titan Ridge



11.1 Supported Thunderbolt™ Configuration Options

Table 11-2. Supported Thunderbolt™ Configuration - Inputs

Thunderbolt Connector Number	PCIe* Configuration	DisplayPort* Sink
1 USB Type-C Connector	x2 or x4(recommend)	1 x4 or 2 x4 (recommend)
2 USB Type-C Connectors	x4	2 x4

Table 11-3. Supported Thunderbolt™ Configuration - Outputs (Sheet 1 of 2)

Thunderbolt Controller	Thunderbolt Link Connection	Side Port Connection
Alpine Ridge DP	2 high speed ports can be configured as: <ul style="list-style-type: none"> Two USB Type-C connectors: <ul style="list-style-type: none"> — Thunderbolt (40G) — or Native DP1.2 — or Native USB 3.1 One USB Type-C connector (as described) and One of the high speed ports can be configured as DP only: <ul style="list-style-type: none"> — could be mDP or DP One USB Type-C connector (as described) and One of the high speed ports can be configured as USB Type-A connector: <ul style="list-style-type: none"> — Native USB3.1 	<ul style="list-style-type: none"> 1 Display connector: <ul style="list-style-type: none"> — HDMI connector - Native HDMI1.4 — or DP connector - Native DP1.2
Alpine Ridge SP	1 high speed port can be configured as: <ul style="list-style-type: none"> One USB Type-C connectors: <ul style="list-style-type: none"> — Thunderbolt (40G) — or Native DP1.2 — or Native USB 3.1 One USB Type-A connector: <ul style="list-style-type: none"> — Native USB3.1 	<ul style="list-style-type: none"> 1 Display connector: <ul style="list-style-type: none"> — HDMI connector - Native HDMI1.4 — or DP connector - Native DP1.2
Alpine Ridge LP	1 high speed port can be configured as: <ul style="list-style-type: none"> One USB Type-C connectors: <ul style="list-style-type: none"> — Thunderbolt (40G) — or Native DP — or Native USB 3.1 One USB Type-A connector: <ul style="list-style-type: none"> — Native USB3.1 	<ul style="list-style-type: none"> No side port supported
Titan Ridge DP	2 high speed ports can be configured as: <ul style="list-style-type: none"> Two USB Type-C connectors: <ul style="list-style-type: none"> — Thunderbolt (40G) — or Native DP1.4¹ — or Native USB 3.1 One USB Type-C connector (as described) and One of the high speed ports can be configured as DP only: <ul style="list-style-type: none"> — could be mDP or DP One USB Type-C connector (as described) and One of the high speed ports can be configured as USB Type-A connector: <ul style="list-style-type: none"> — Native USB3.1 	<ul style="list-style-type: none"> 1 Display connector: <ul style="list-style-type: none"> — DP connector - Native DP1.4¹
Titan Ridge SP	1 high speed port can be configured as: <ul style="list-style-type: none"> One USB Type-C connectors: <ul style="list-style-type: none"> — Thunderbolt (40G) — or Native DP1.4¹ — or Native USB 3.1 One USB Type-A connector: <ul style="list-style-type: none"> — Native USB3.1 	<ul style="list-style-type: none"> 1 Display connector: <ul style="list-style-type: none"> — DP connector - Native DP1.4¹

**Table 11-3. Supported Thunderbolt™ Configuration - Outputs (Sheet 2 of 2)**

Thunderbolt Controller	Thunderbolt Link Connection	Side Port Connection
Note: 1. DP1.4 support will depend on GPU capability		

11.2 Thunderbolt™ Port Power Requirements

11.2.1 Host Source Requirements

Single Port Hosts are required to minimally support 3A/5V on VBUS in Thunderbolt Mode.

Hosts with more than one port are required to provide power per [Table 11-4](#). All Thunderbolt ports shall be capable of providing Full VBUS power on a first-come, first-served basis up to the minimum number of required ports. Tablet PCs with screen sizes less than 13.x" shall provide a minimum of 4.5W on all Thunderbolt ports.

Thunderbolt Hosts shall provide 1.5W to the VCONN pin on all Thunderbolt ports. The VCONN voltage is required to be between 4.75V and 5.5V per USB Type-C r1.0. Note that 1.5W power from VCONN is higher than the 1.0W required by USB Type-C r1.0.

All Ports shall use the termination defined in Table 4-10 in USB Type-C r1.0 to broadcast their available Source current. The DFP/Source shall modify its termination to reflect any changes in Source current availability. Thunderbolt Ports shall use the 3.0A/5V pull-up.

Hosts must be DRPs to be able to support peer-to-peer communication.

Table 11-4. VBUS Power Provisioning with Number of Thunderbolt™ Ports

Power Standard	Voltage/Current	Port 1	Port 2	Port 3	Port 4
First Port VBUS Power	5V/3A	1	1	2	2
Second Port VBUS Power	5V/900mA	NA	1	1	2
VCONN Power	1.5W TBT	1	2	3	4

11.3 Power Delivery

Refer to **USB PD r2.0** power compliance document for the compliance measurements. The document can be downloaded from <http://www.usb.org>.

11.3.1 Thunderbolt™ Power Provider VBUS Electrical Requirements

The VBUS Source Electrical Parameters are specified in Table 7-22 and Table 7-24 of the USB PD r2.0 Specification. The VCONN Source requirements are specified in Table 4-2 and Table 4-3 of the USB Type-C r1.0 Specification. The only specifications defined here are those which differ from or are in addition to the USB PD r2.0 and the USB Type-C r1.0 Specifications. This specification assumes compliance with USB Type-C r1.0 specification with additional conditions specifically required for Thunderbolt.



Thunderbolt Power Providers must supply 5V and shall use the Fixed Voltage PDO. The current has been chosen to yield 10.5W worst-case for a bus powered device after the switching regulator assuming 88% efficiency at 5V. The requirements for Power Provides is shown in table below.

Optional VBUS sources can provide 9V, 15V and 20V following the USB PD r2.0 Specification.

USB Type-C and USB PD specification can be downloaded from <http://www.usb.org>.

Table 11-5. Thunderbolt™ VBUS Source Electrical Parameters

Parameter	Description	Min	Typ	Max	Units	Note
VSrc_BPD5 ¹	Minimum voltage provided to port in Active when connected to a BPD	4.75	5	5.5	V	3A min current

Note: 1. Thunderbolt Specific Requirement

11.3.2 Thunderbolt™ VCONN Source Electrical Requirements

The Thunderbolt Power Provider VCONN Electrical Parameters are specified in table below.

Table 11-6. Thunderbolt VCONN Source Electrical Requirements

Parameter	Description	Min	Typ	Max	Units	Note
VSrc_Susp	Minimum voltage provided to port in suspend	4.75	5	5.5	V	7.5mA min
VSrc_Active	Minimum power provided to port in Active	4.75	5	5.5	V	1.5W min

11.3.3 Thunderbolt™ BIOS

Thunderbolt™ introduces multilevel PCIe* trees with multiple bridges and endpoint devices. Windows* 10 RedStone2 and the versions before do not have fully built-in support for Thunderbolt™. Thunderbolt™ uses the native PCIe* driver in the OS, and supports hot plug/unplug via the BIOS.

For Windows* 10 RedStone3 and later versions, Thunderbolt™ hot plug/unplug are supported by native PCIe* driver.

Thunderbolt™ BIOS includes three main aspect,

1. Thunderbolt™ Hot Plug/unplug

Hot plug is a standard PCIe* feature and current Windows* OS only supports simple PCIe topologies. In general case, Thunderbolt™ introduces multilevel PCIe trees with multiples bridge and endpoint device. Current Windows* OS does not have built-in support for Thunderbolt™. In order to prevent PCIe* wrong resource allocation and misconfiguration, Thunderbolt™ BIOS uses ACPI issues software SMI and upon completion Notify (RP01,0) to trigger OS rescan of the underlying PCIe* sub-tree.

2. Security Levels

Alpine/Titan Ridge supports different levels of security for device connection and PCIe* tunneling. Table below defines Alpine/Titan Ridge support security level, and default security level is Security Level 1 (SL1).

Table 11-7. Supported Alpine/Titan Ridge Security Level

SL#	Security Level	Description
SL0	No Security	Allow legacy Thunderbolt devices auto connect - the connection manager auto connects to a new device plugged in
SL1	User Authorization	Allow User Notification devices - the connection manager requests connection approval from the host SW, auto approval may be given based on the Unique ID of the connecting device
SL2	Secure Connect	Allow One time saved key devices - the connection manager requests connection approval from the host SW, auto approval is only given if the host challenge to the device is acceptable
SL3	DisplayPort only	Allow only DP sinks to be connected (re-driver or DP tunnel, no PCIe* tunneling) - at this mode no tunneling is done for PCIe devices

3. Sx Handling

Tables below lists Alpine/Titan Ridge wake support enabled and disabled configuration. If mobile platform wants to enable wake support on some power state only, BIOS should know the host is at what power state, and then follow WakeEnabled flow or WakeDisabled flow. For System For systems that provide Alpine/Titan Ridge power from two separate rails (VCC3P3_SX from a sustain rail while VCC3P3_S0 from S0 rail) the system must perform a pre-notice Sx entry procedure through the TBT2PCIe mailbox. For the case Alpine/Titan Ridge is not powering the CIO domain the BIOS needs to force Alpine/Titan Ridge power using POC_GPIO_3 to enable the mailbox functionality.

Table 11-8. Alpine/Titan Ridge S3/S4 Wake Support Enabled

	S3/S4 WakeEnabled	S5
HW requirement	<ul style="list-style-type: none"> Connect SLP_S3# to AR/TR GPIO Keep AR Power VCC3P3_S0 and VCC3P3_SX power rails similar to S0 	Power off AR
Sx Entry	SLP_S3: asserted (high->low)	RESET_N: asserted (high->low)
Sx (expected behavior)	CM shutdown "CIO", "RDV", "LC" power domains	0 mW
If Batlow# asserted during Sx	Wake feature will be disabled	N/A
Sx Exit	<ul style="list-style-type: none"> SLP_S3#: deasserted Wake from TBT device - AR/TR will assert PCIE_WAKE_N until PERST_N is deasserted. <p>PCIE_WAKE_N will not be asserted if AR/TR Host woke up due to SLP_S3# deassertion</p>	Same as TBT power on sequence

Table 11-9. Alpine/Titan Ridge S3/S4 Wake Support Disabled

	S3/S4 WakeDisabled	S5
HW requirement	Power off AR(Vcc3v3)	Power off AR(Vcc3v3)
Sx Entry	<ul style="list-style-type: none"> RESET_N: asserted (high->low) Power off AR/TR 	<ul style="list-style-type: none"> RESET_N: asserted (high->low)
Sx (expected behavior)	0 mW	0 mW
If Batlow# asserted during Sx	N/A	N/A
Sx Exit	Check if TBT device is connected or not before Sx Entry — Write PCIE2TBT mailbox	Same as TBT power on sequence



For detailed Thunderbolt BIOS specification and reference code, refer to "Alpine/Titan Ridge - Thunderbolt BIOS Implementation Guide" and "Alpine/Titan Ridge - Thunderbolt BIOS Additions".

11.3.4 Reference Documents

Title	Document #
Alpine Ridge DP Collateral	563553
Alpine Ridge SP Collateral	549740
Alpine Ridge LP Collateral	560284
Titan Ridge DP Collateral	567677
Titan Ridge SP Collateral	573973
Thunderbolt - Alpine Ridge C0 NVM image	565187
Thunderbolt - Titan Ridge B0 NVM image	573500
Thunderbolt TenLira Tool	559533
Imaginarium 2- For Alpine Ridge Thunderbolt products	559314
Manufacturing Test with Intel® Thunderbolt™ Technology Premium IO Controller Host	559414

11.3.5 Compliance Specification

Table 11-10. Thunderbolt™ Compliance Specification

Title	Document #
Thunderbolt - USB Type-C TBT Specification	557111
Thunderbolt - Host Electrical Validation Test Specification	567664
Thunderbolt 3 Based PC Host Functional Compliance Test Specification	557133

11.3.6 Thunderbolt™ Signal Descriptions

Table 11-11. Thunderbolt™ High Speed Interface

Interface	Description	Bit Rate
TBT	Thunderbolt™ 20Gbps channel	20.625 Gb/s
USB3.1	USB3.1 10Gbps channel	10 Gb/s
PCIe* Gen3	Used for PCIe root complex connection	8 GT/s
DisplayPort* 1.2a	Used for DP Sink connection	5.4 Gb/s
DisplayPort* 1.4 ¹	Used for DP Sink connection	8.1 Gb/s
USB* 2	Used for USB 2.0connection	480 Mb/s

Note: 1. 8.1Gbps is only supported on Titan Ridge



11.3.6.1 Thunderbolt™ Controller Signal Groups

Table 11-12. Alpine/Titan Ridge High Speed Signals

Group	Signal Name	Description
TBT Tx	<ul style="list-style-type: none">Alpine RidgeTBTA_HD2CA_0_P, TBTA_HD2CA_0_NTBTA_HD2CA_1_P, TBTA_HD2CA_1_NTBTB_HD2CA_0_P, TBTB_HD2CA_0_NTBTB_HD2CA_1_P, TBTB_HD2CA_1_N	TBT Transmitter Differential Pair
	<ul style="list-style-type: none">Titan RidgeTBTA_TX1_P, TBTA_TX1_NTBTA_RX2_P, TBTA_RX2_NTBTB_RX1_P, TBTB_RX1_NTBTB_RX2_P, TBTB_RX2_N	
TBT Rx	<ul style="list-style-type: none">Alpine RidgeTBTA_CA2HD_0_P, TBTA_CA2HD_0_NTBTA_CA2HD_1_P, TBTA_CA2HD_1_NTBTB_CA2HD_0_P, TBTB_CA2HD_0_NTBTB_CA2HD_1_P, TBTB_CA2HD_1_N	TBT Receiver Differential Pair
	<ul style="list-style-type: none">Titan RidgeTBTA_RX1_P, TBTA_RX1_NTBTA_RX2_P, TBTA_RX2_NTBTB_RX1_P, TBTB_RX1_NTBTB_RX2_P, TBTB_RX2_N	
PCIe* Tx	PCIE_TX[3:0]_P, PCIE_TX[3:0]_N	PCIe* Transmitter Differential Pair
PCIe* Rx	PCIE_RX[3:0]_P, PCIE_RX[3:0]_N	PCIe Receiver Differential Pair
DP Sink	DPSNK0_ML[3:0]_N, DPSNK0_ML[3:0]_P, DPSNK1_ML[3:0]_N, DPSNK1_ML[3:0]_P	DP Sink Main Link Receiver Differential Pair
USB 2	PA_USB2_D_N, PA_USB2_D_P, PB_USB2_D_N, PB_USB2_D_P	USB 2.0 Differential Pair

11.4 Thunderbolt™ Topology Guidelines

11.4.1 Motherboard Down Topology

Thunderbolt™ I/O is a virtual wire from PC point of view that tunnels PCIe* and DisplayPort* stream. Considering PCIe*/DisplayPort* connection and few GPIOs for BIOS implementation, Thunderbolt controller onboard design is highly recommended. External DisplayPort* cable and GPIO cable may cause bad user experience, for example, no video or no Hot Plug support.



11.4.2 DisplayPort* to Thunderbolt™ Topology

Figure 11-1. CFL DisplayPort Main link Direct Motherboard Topology for TBT

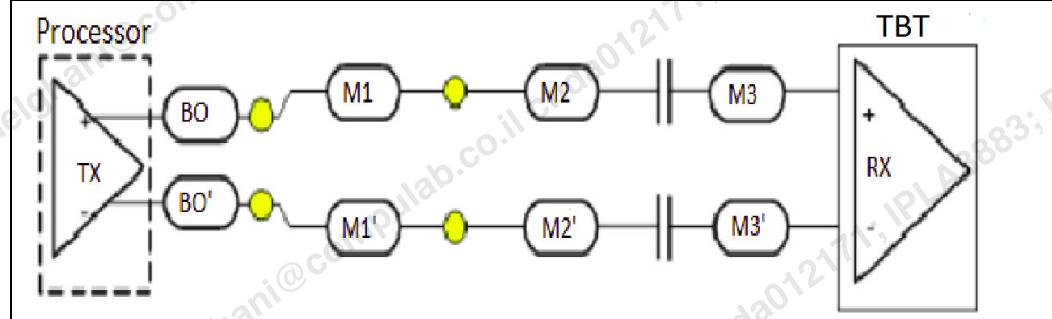


Table 11-13. CFL DisplayPort to TBT Main Link Routing Guideline

Figure 11-2. CFL DisplayPort for TBT Aux link Direct topology

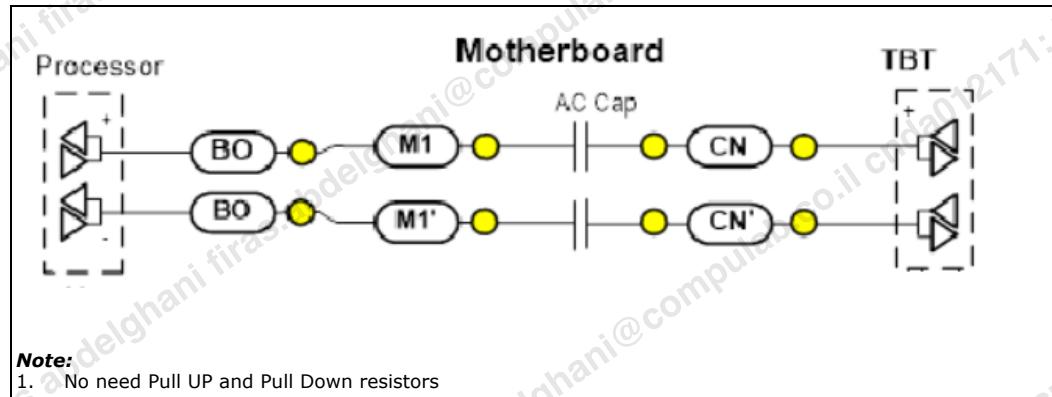


Table 11-14. CFL DisplayPort to TBT AUX Link Routing Guidelines

Segment	Stack-up	Via Count	Max Length [mils]
B0	MS/SL	No explicit limit, use best known routing practices	700
M1	MS/SL/DSL		7000
CN	MS/SL/DSL		7000
Total Length			13000

11.4.3 Add-In Card Topology

Table 11-15. Thunderbolt™-ready Motherboard Requirement (Sheet 1 of 2)

PCIe* Slot	PCIe x4 or wider slot from the PCH <ul style="list-style-type: none"> Recommend 4 PCIe lanes are routed to the PCIe slot If only 2 PCIe lanes are routed to the PCIe slot the board must state support for only 10Gbps of data, this must be shown on the compatible motherboard list
Pre-loaded BIOS	Refer to Thunderbolt BIOS implementation

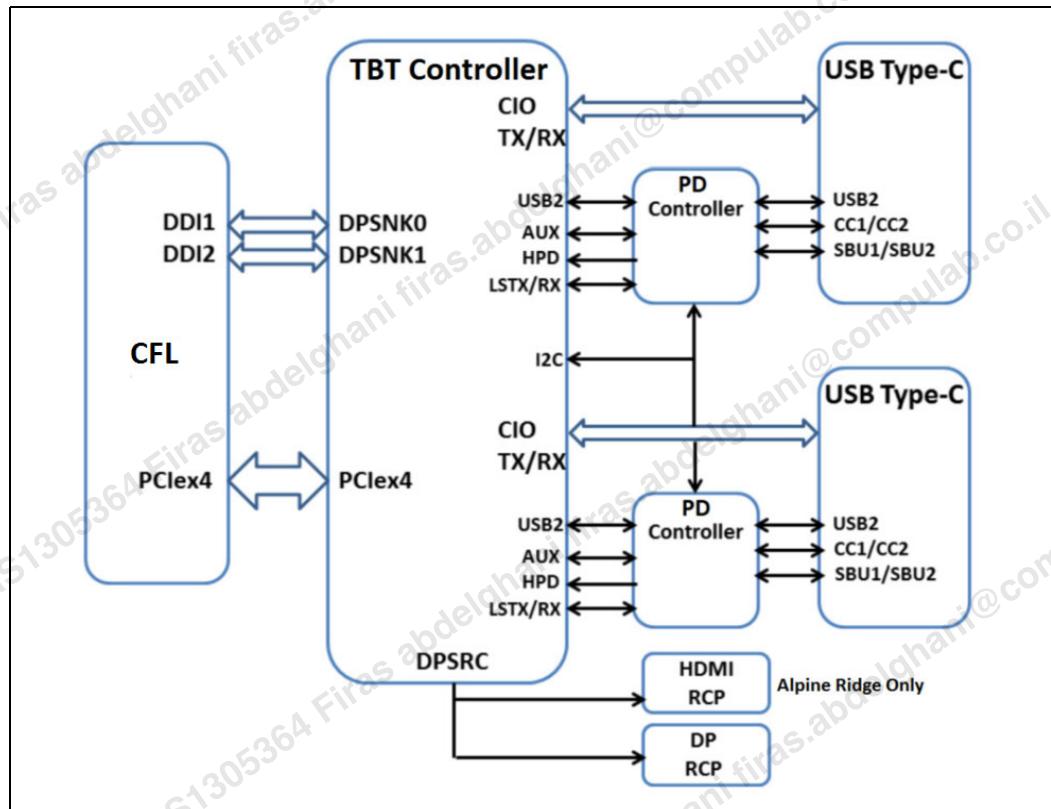
Table 11-15. Thunderbolt™-ready Motherboard Requirement (Sheet 2 of 2)

GPIO Header	<ul style="list-style-type: none"> Pin1: Force Power - Output pin from PCH/EC/SIO GPIO for security level and debug purpose Pin2: No Connect Pin3: CIO Plug Event - Input pin from PCH GPIO which support SMI/SCI event for hot-plug and surprising removal Pin4: I2C_MASTER_DATA Pin5: SLP_S3# - SLP_S3# from PCH for S3 control Pin6: I2C_MASTER_CLK Pin7: SLP_S5_S4# - SLP_S5# from PCH for S4/S5 control Pin8: PA_PPS_INT# Pin9: GND Pin10: GND
DP output	<ul style="list-style-type: none"> For Z, H and Q chipset boards a standard DP out connector (from processor graphics) must be available on the board For X chipset boards the DP must come from the graphics add-in card

11.4.4 Thunderbolt™ Connector Guideline

Refer to USB Type-C specification. The document can be downloaded from <http://www.usb.org>.

11.5 Thunderbolt™ Length Matching Guidelines

Figure 11-3. Thunderbolt™ Host Reference Design Block Diagram




Group	Segment	Max Length		Differential Impedance	Length Matching within Diff Pair		
		mm (max)	mils (max)				
TBT Tx	<ul style="list-style-type: none"> Alpine Ridge TBTA_HD2CA_0_P, TBTA_HD2CA_0_N TBTA_HD2CA_1_P, TBTA_HD2CA_1_N TBTB_HD2CA_0_P, TBTB_HD2CA_0_N TBTB_HD2CA_1_P, TBTB_HD2CA_1_N 	50.8	2000	90 Ohm ± 5%	N/A		
	<ul style="list-style-type: none"> Titan Ridge TBTA_TX1_P, TBTA_TX1_N, TBTA_TX2_P, TBTA_TX2_N, TBTB_TX1_P, TBTB_TX1_N, TBTB_TX2_P, TBTB_TX2_N, 			85 Ohm ± 10%			
TBT Rx	<ul style="list-style-type: none"> Alpine Ridge TBTA_CA2HD_0_P, TBTA_CA2HD_0_N TBTA_CA2HD_1_P, TBTA_CA2HD_1_N TBTB_CA2HD_0_P, TBTB_CA2HD_0_N TBTB_CA2HD_1_P, TBTB_CA2HD_1_N 	50.8	2000	90 ohm ± 5%	N/A		
	<ul style="list-style-type: none"> Titan Ridge TBTA_RX1_P, TBTA_RX1_N, TBTA_RX2_P, TBTA_RX2_N, TBTB_RX1_P, TBTB_RX1_N, TBTB_RX2_P, TBTB_RX2_N, 			85 Ohm ± 10%			
PCIe*	PCIE_TX[3:0]_P, PCIE_TX[3:0]_N PCIE_RX[3:0]_P, PCIE_RX[3:0]_N	For matching methodology, refer to Chapter 16, "PCH PCI Express* Interface Design Guidelines" and Chapter 3, "General Differential Design Guidelines"					
DisplayPort*	DPSNK0_ML[3:0]_N, DPSNK0_ML[3:0]_P, DPSNK1_ML[3:0]_N, DPSNK1_ML[3:0]_P	For matching methodology, refer to Chapter 5, "DisplayPort* Design Guidelines" and Chapter 3, "General Differential Design Guidelines".					



11.6 Thunderbolt™ Stack-up Guidelines

11.6.1 Stack-up and Layer Utilization Guidelines

Table 11-16. Thunderbolt™ Layer Utilization

Group	Max Number of Vias Allowed	Routing Layer	Pair-to-Pair Spacing	Pair to other (via, trace, component) spacing
TBT Tx	2 (See Note1)	Top Layer	>3h mil	>3h mil
TBT Rx	2 (See Note1)	Bottom Layer	>3h mil	>3h mil

Note:

1. For mid-mount USB-C connector, PA_TX0, PB_TX0, PA_RX1, PB_RX1 connect to USB-C without Vias, PA_TX1, PB_TX1, PA_RX0, PB_RX0 connect to USB-C with 2 PTH Vias

11.6.2 Thunderbolt™ Insertion Loss Spec

Thunderbolt Link Frequency	Insertion Loss Budget on PCB	Reserved Budget for AR Package and Receptacle	Total Insertion Loss Budget
@5.15625Ghz (10.3125Gbps)	2dB	1.5dB	3.5dB
@10.3125Ghz (20.625Gbps)	4dB	3.5dB	7.5dB

11.7 Thunderbolt™ Optimization Guidelines

11.7.1 TBT Lane Routing and Component Placement

Refer to “Alpine Ridge Host DP - Layout Guideline” for detailed layout recommendation. Doc. ID: 563553.

11.7.2 Via Placement and Via Pad Optimization

TBT lane differential routing makes layer transition, the “Top2Bottom Via” unused via pads and Thunderbolt connector DIP pin pads in the middle layers should be removed. Use the smallest possible Vias on board to optimize the impedance for the CIO interface.

11.8 Thunderbolt™ Debug Guidelines

11.8.1 PCIe* and DisplayPort* Configuration

For supported PCIe* configuration options, refer to Chapter 15, “PCH PCI Express* interface Design Guidelines”. It is recommended to use any tools and utility to check PCIe link width between Alpine/Titan Ridge and Coffee Lake processor.

For DisplayPort* configuration, refer to [Chapter 5, “DisplayPort* Design Guidelines”](#). VBIOS and 3 independent display configurations are also needed to be taken into consideration.



11.8.2 NVM Configuration

Alpine/Titan Ridge support lane reversal mode such that the polarity traces (P/N) of a CIO/DP lane differential pair can be swapped (to N/P) for ease of routing. System developers must modify Alpine/Titan Ridge NVM setting (interface, offset, and value) to match the P/N configuration as used in actual lane trace routing. Refer to "Thunderbolt – Alpine/Titan Ridge NVM Image" for the latest release note about the offset/value setting for specific CIO/DP lanes. Each revision might have different instructions on how to control board-dependent channels lanes N/P swap configuration.

11.9 Thunderbolt™ Additional Guidelines

11.9.1 Crystal Design Requirement

Refer to 5.4.2 of "Alpine/Titan Ridge datasheet" for detailed XTAL/Clock specification. Doc. ID: 563553/567677

11.9.2 NVM

Alpine/Titan Ridge use Flash memory for initialization of various internal parameters, enable/disable bits, analog modules configuration, and internal microcontrollers' ucode patches. Refer to chapter 3 of "Alpine/Titan Ridge datasheet" for more detailed Flash memory map.

Table 11-17. Supported Flash for Alpine/Titan Ridge

Manufacturer	Type	Volume (Mbit)	Supply Voltage (V)
AMIC*	A25L080	8.0	3.0-3.6
Spansion*	S25FL208K	8.0	2.7-3.6
Winbond*	W25Q80JVNIQ	8.0 (8pin SOIC150 mil)	2.7-3.6
Macronix*	MX25L8006EM1I	8.0 (150mil, 8-SOP)	2.7-3.6
Micron*	M25PE80-VMN6TP	8.0 (150mil, SO8N)	2.7-3.6
Micron*	M25PX80-VMN6TP	8.0 (150mil, SO8N)	2.7-3.6

11.9.3 Thunderbolt Native PCIe* Mode

Thunderbolt native PCIe* mode is supported on Windows* 10 RedStone3 and later versions. Enabling native PCIe* mode on TBT provides benefits including the full support of Modern Standby, less platform BIOS development and validation efforts and shorter device enumeration time.

11.9.4 Modern Standby and Runtime D3 Support

Thunderbolt controllers support PCIe link states such as L1 sub-states (Titan Ridge only), L2 and link disconnect to enable SoC to enter low CPU C-States and PCH to assert SLP_S0# to control voltage regulators or embedded controllers to turn off power rails to reduce platform power. If the device, or any other PCIe connected device does not support minimum PCIe low power states, SoC and platform low power states will be blocked and power consumption will be higher.

Refer to Coffee Lake Runtime D3 (RTD3) Hardware and Software Recommendations Design Guide for PCIe* RTD3 implementation details. Doc. ID: 569310.



Modern Standby and RTD3 support with Thunderbolt is supported on Windows* 10 RedStone3 and later versions with native PCIe* mode enabled.

11.9.5

Hardware Changes to Support TBT PCIe* RTD3

The following changes are needed to support TBT PCIe* RTD3 in hardware. These pins must be connected to dedicated PCH GPIO pins.

1. TBT_PERST_N: Signal must be isolated to allow a device D3(cold) exit to occur without impacting other endpoints, with facilities to drive the required signal timing (e.g. via ACPI and/or Platform Driver).
2. TBT_PCIE_WAKE_N: Use of the WAKE pin for device-initiated wake during D3(cold) without disrupting other devices.
3. RTD3_PWR_EN: Ability to coordinate/sequence power applied to a D3(cold) domain. This pin must be connected to TBT controller directly instead of connecting to an external MOSFET that controls the power of TBT controller.
4. TBT_CLKREQ_N: Connect to dedicated PCH PCIe* Clock Request pin.

Note:

These four signals are named as DG_PERST#, DG_PEWAKE#, DG_RTID3_PWR_EN and DG_CLKREQ# in Titan Ridge Reference Design.

§ §

12 Clock and Low Speed I/Os

12.1 Platform Clock Design Guidelines

12.1.1 Platform Clock Interface Details

Figure 12-1. Clock Integration Distribution Diagram

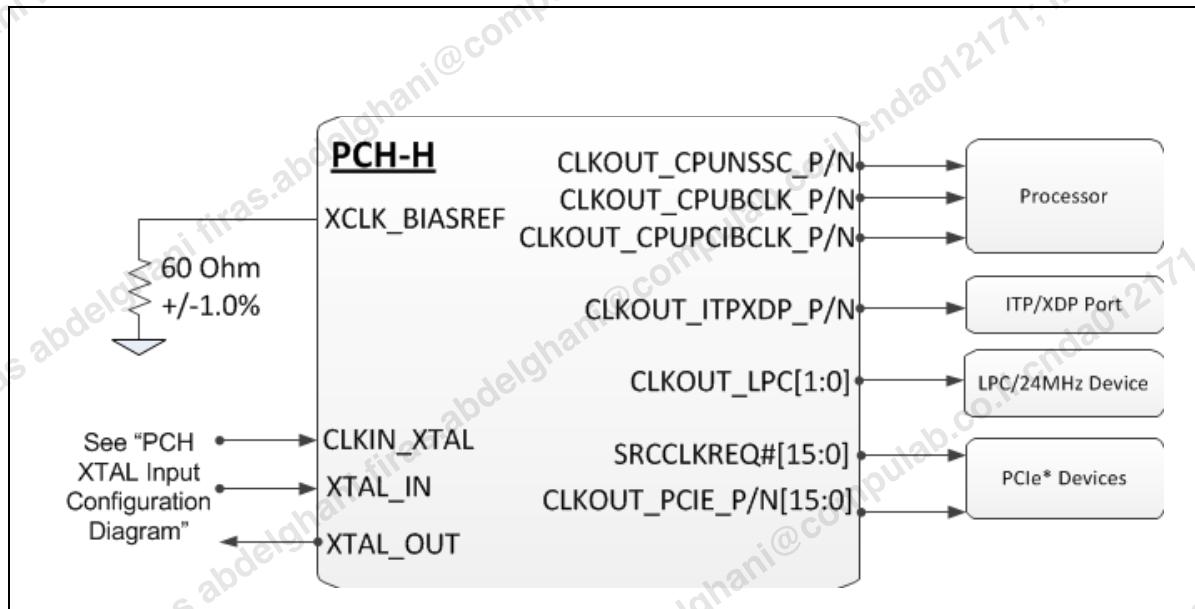
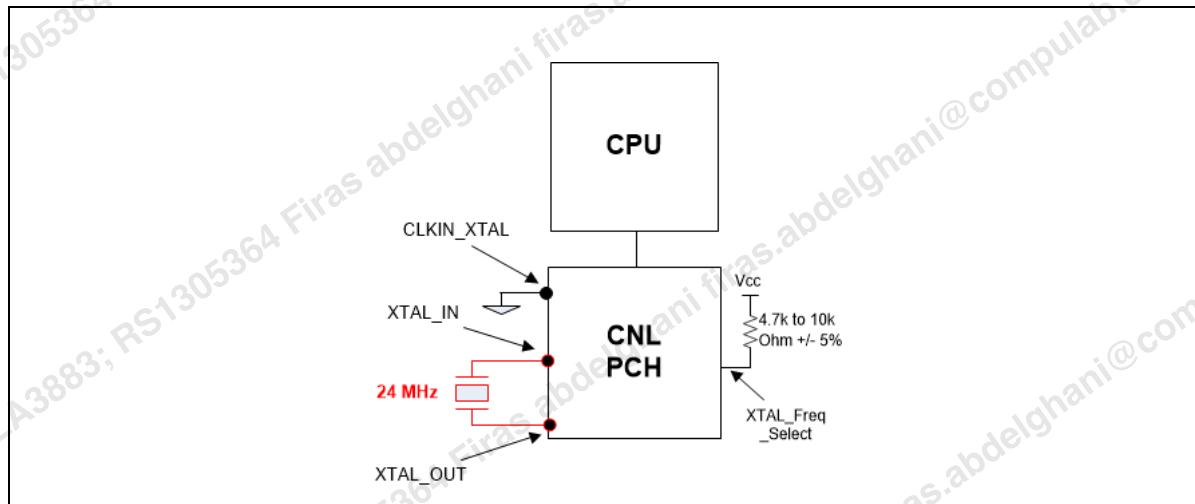


Figure 12-2. PCH XTAL Input Configuration Diagram





12.1.2 Platform Clock Signal Descriptions

Table 12-1. Platform Clocks and Associated Signal Details and Descriptions

Signal Name	Type	SSC Capable	Description
CLKOUT_CPNSSC_P CLKOUT_CPNSSC_N	O	No	Filtered Crystal Reference Clock to CPU: 24MHz differential, filtered crystal reference clock to the processor
CLKOUT_CPBCLK_P CLKOUT_CPBCLK_N	O	Yes	Differential Clock to CPU: Reference clock to the processor 100-MHz differential core
CLKOUT_CPUPCIIBCLK_P CLKOUT_CPUPCIIBCLK_N	O	Yes	Differential PCIe* Reference Clock to CPU: 100-MHz PCIe* 3.0 specification compliant differential PCIe* reference clock to the processor
CLKOUT_ITPXDP_P CLKOUT_ITPXDP_N	O	Yes	Differential ITP Debug Clock: 100 MHz differential output to processor XDP/ITP connector on the platform
CLKOUT_PCIE_P[15:0] CLKOUT_PCIE_N[15:0]	O	Yes	PCI Express* Clock Output: Serial Reference 100 MHz PCIe* 3.0 specification compliant differential output clocks to PCIe* devices
CLKOUT_LPC[1:0]	O	No	Low Pin Count (LPC) Clock Outputs: Single-Ended 24-MHz output to various single load connectors/devices
SRCCCLKREQ#[15:0]	I/O		Clock Request: Serial Reference Clock request signals for PCIe* 100 MHz differential clocks
XTAL_IN	I		Crystal Input: Input connection for 24MHz crystal to PCH
XTAL_OUT	O		Crystal Output: Output connection for 24 MHz crystal to PCH
XCLK_BIASREF	I/O		Differential Clock Bias Reference: Used to set BIAS reference for differential clocks
CLKIN_XTAL	I		XTAL Clock Input: Single ended integrated CNV (Connectivity) XTAL clock input
XTAL_Freq_Select (GPP_J4)			XTAL Frequency Select: GPP_J4 Pin Strap for XTAL frequency selection. An external pull-up to VCC (1.8V) is required on this strap for 24 MHz XTAL operation

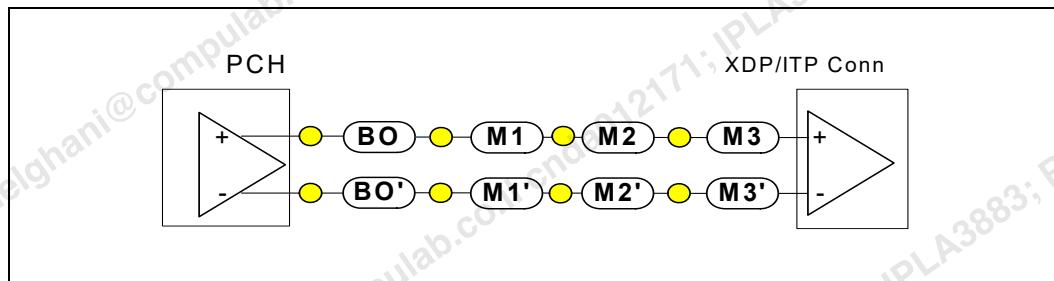
Note:

1. SSC = Spread Spectrum Clocking
2. The SRCCCLKREQ#[15:0] signals can be configured to map to any of the PCH-H PCI Express* Root Ports
3. SRCCCLKREQ#[15:0] to CLKOUT_PCIE_P/N[15:0] Mapping Requirements
 - SRCCCLKREQ#[7:0] signals can be mapped to any of the CLKOUT_PCIE_P/N[7:0] differential clock pairs
 - SRCCCLKREQ#[15:8] signals can be mapped to any of the CLKOUT_PCIE_P/N[15:8] differential clock pairs

12.2 Platform Clock Guidelines

12.2.1 ITP_XDP Differential Clock Routing Guidelines

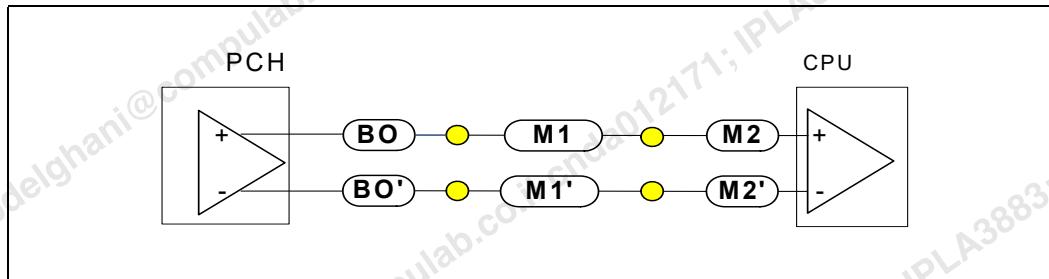
- Differential Clock Signals:
 - CLKOUT_ITPXDP_P/N

Figure 12-3. ITP_XDP Differential Clock Topology**Table 12-2. ITP_XDP Differential Clock Routing Guidelines**

Parameter	Segment	Stack-up	Rule
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	Ground
Max Segment Length	BO	MS/SL/DSL	12.7mm(500mils)
	M3	MS	25.4mm(1000mils)
Total Motherboard Length	BO+M1+M2+M3	MS/SL/DSL	101.6mm(4000mils) to 304.8mm(12000mils)
Differential Pair Length Matching	Within Same Layer	MS/SL/DSL	$\pm 0.254\text{mm} (\pm 10\text{mils})$
	Total (B0+M1+M2+M3)	MS/SL/DSL	$\pm 0.381\text{mm} (\pm 15\text{mils})$
Max Transition Via Count	BO		1
	M1, M2		2
	M3		1
Notes:			
1. BO = Motherboard Break Out Segment, M = Motherboard Main Segments			
2. MS = Micro-Strip, SL = Strip-Line, DSL = Dual Strip-Line			
3. Continuous Ground Referencing is required. If needed power plane referencing to +V1p0 is allowed in the Motherboard Break Out (B0) Segment			
4. Clock traces are to be routed in a differential configuration with minimum coupling between the P/N differential signals; where the signals within a differential pair must route together for their entire route.			
5. Do not place vias between adjacent complementary clock traces and avoid any differential vias. Vias that are placed in one signal of a differential pair must be matched by a via in the complement signal within a differential pair.			
6. At least one ground stitching via must be placed within 30mils(0.762mm) from every signal transition via when ever they change signal layers.			
7. If this differential clock pair is not being used it must be left as a no connect			
8. Refer to details covered in the "Stack-Up and PCB Considerations" chapter for Trace Impedance, Differential Spacing, Group Spacing, and Isolation Spacing requirements			

12.2.2 CPU Differential Clock Routing Guidelines

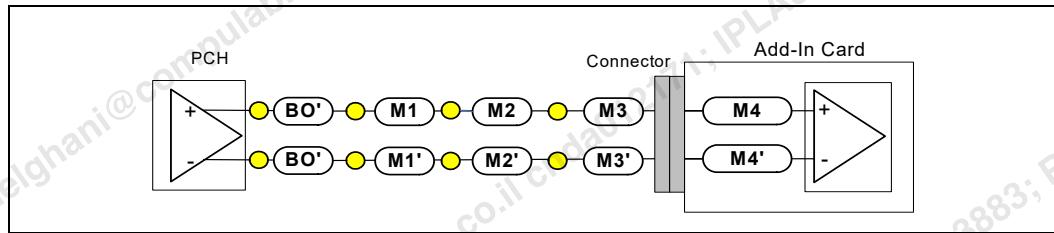
- CPU Differential Clock Signals:
 - CLKOUT_CPNUNSSC_P/N
 - CLKOUT_CPUUPCIBCLK_P/N
 - CLKOUT_CPUTUBCLK_P/N

Figure 12-4. CPU Differential Clock Topology

Table 12-3. CPU Differential Clock Routing Guidelines

Parameter	Segment	Stack-up	Rule
Reference Plane	BO, M1, M2	MS/SL/DSL	Ground
Max Segment Length	BO	MS/SL/DSL	12.7mm(500mils)
	M2	MS/SL/DSL	12.7mm(500mils)
Total Motherboard Length	BO+M1+M2	MS/SL/DSL	101.6mm(4000mils) to 228.6mm(9000mils)
Differential Pair Length Matching	Within Same Layer	MS/SL/DSL	$\pm 0.254\text{mm}$ ($\pm 10\text{mils}$)
	Total (B0+M1+M2+M3)	MS/SL/DSL	$\pm 0.381\text{mm}$ ($\pm 15\text{mils}$)
Pair to Pair Length Matching	Total (B0+M1+M2+M3)	MS/SL/DSL	$\leq 12.7\text{mm}$ (500mils)
Max Transition Via Count	BO		1
	M2		1
Notes:			
1. BO = Motherboard Break Out Segment, M = Motherboard Main Segments			
2. MS = Micro-Strip, SL = Strip-Line, DSL = Dual Strip-Line			
3. Continuous Ground Referencing is required. If needed power plane referencing to +V1p0 is allowed in the Motherboard Break Out (B0) Segment			
4. Clock traces are to be routed in a differential configuration with minimum coupling between the P/N differential signals; where the signals within a differential pair must route together for their entire route.			
5. Do not place vias between adjacent complementary clock traces and avoid any differential vias. Vias that are placed in one signal of a differential pair must be matched by a via in the complement signal within a differential pair.			
6. At least one ground stitching via must be placed within 30mils(0.762mm) from every signal transition via when ever they change signal layers.			
7. Pair to Pair Length Matching = Length Matching between all CPU Differential Clock Signals			
8. Refer to details covered in the "Stack-Up and PCB Considerations" chapter for Trace Impedance, Differential Spacing, Group Spacing, and Isolation Spacing requirements			
9. For the M1/M1' segment it is recommended to route the CPU Differential Clock Signals on inner layers, SL or DSL, GND Referenced with solid GND Floods on both sides (if applicable) to help mitigate any RFI impacts. If Micro-strip routing is used for the M1/M1' segment it is recommended that it be limited, if possible, to a maximum length of 25.4mm (1000mils). For additional details reference the "Electromagnetic Compatibility" chapter.			

12.2.3 PCIe* Differential Clock Routing Guidelines to Add-in Card

- Serial Reference Differential Clock Signals:
 - CLKOUT_PCIE_P/N[15:0]

Figure 12-5. PCIe* Differential Clock to Add-in Card Topology**Table 12-4. PCIe* Differential Clock to Add-in Card Routing Guidelines**

Parameter	Segment	Stack-up	Rule
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	Ground
Max Segment Length	BO	MS/SL/DSL	12.7mm(500mils)
	M3	MS	25.4mm(1000mils)
	M4	MS	50.8mm(2000mils)
Total Motherboard Length	BO+M1+M2+M3	MS/SL/DSL	101.6 mm(4000mils) to 254mm(10000mils)
Differential Pair Length Matching	Within Same Layer	MS/SL/DSL	$\pm 0.254\text{mm}$ ($\pm 10\text{mils}$)
	Total (BO+M1+M2+M3)	MS/SL/DSL	$\pm 0.381\text{mm}$ ($\pm 15\text{mils}$)
Max Transition Via Count	BO		1
	M1, M2		2
	M3		1

Notes:

1. BO = Motherboard Break Out Segment, M = Motherboard Main Segments
2. MS = Micro-Strip, SL = Strip-Line, DSL = Dual Strip-Line
3. Continuous Ground Referencing is required. If needed power plane referencing to +V1p0 is allowed in the Motherboard Break Out (BO) Segment
4. Clock traces are to be routed in a differential configuration with minimum coupling between the P/N differential signals; where the signals within a differential pair must route together for their entire route.
5. Do not place vias between adjacent complementary clock traces and avoid any differential vias. Vias that are placed in one signal of a differential pair must be matched by a via in the complement signal within a differential pair.
6. At least one ground stitching via must be placed within 30mils(0.762mm) from every signal transition via when ever they change signal layers.
7. Any differential clock pair not being used must be left as no connects
8. Refer to details covered in the "Stack-Up and PCB Considerations" chapter for Trace Impedance, Differential Spacing, Group Spacing, and Isolation Spacing requirements

12.2.4 PCIe* Differential Clock to Down Device Routing Guidelines

- Serial Reference Differential Clock Signals:
 - CLKOUT_PCIE_P/N[15:0]

Figure 12-6. PCIe* Differential Clock to Down Device Topology

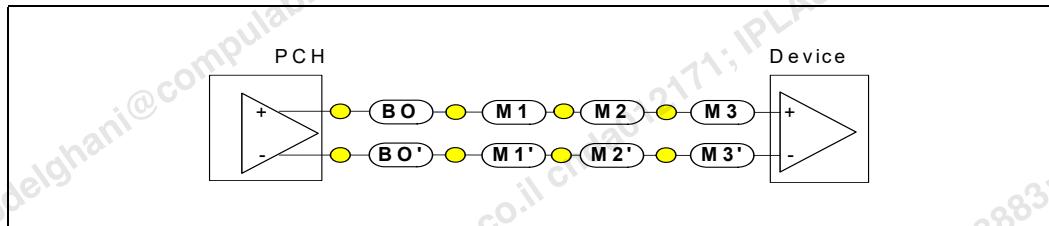


Table 12-5. PCIe* Differential Clock to Down Device Routing Guidelines

Parameter	Segment	Stack-up	Rule
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	Ground
Max Segment Length	BO	MS/SL/DSL	12.7mm(500mils)
	M3	MS	25.4mm(1000mils)
Total Motherboard Length	BO+M1+M2+M3	MS/SL/DSL	101.6 mm(4000mils) to 304.8mm(12000mils)
Differential Pair Length Matching	Within Same Layer	MS/SL/DSL	$\pm 0.254\text{mm} (\pm 10\text{mils})$
	Total (BO+M1+M2+M3)	MS/SL/DSL	$\pm 0.381\text{mm} (\pm 15\text{mils})$
Max Transition Via Count	BO		1
	M1, M2		2
	M3		1

Notes:

1. BO = Motherboard Break Out Segment, M = Motherboard Main Segments
2. MS = Micro-Strip, SL = Strip-Line, DSL = Dual Strip-Line
3. Continuous Ground Referencing is required. If needed power plane referencing to +V1p0 is allowed in the Motherboard Break Out (BO) Segment
4. Clock traces are to be routed in a differential configuration with minimum coupling between the P/N differential signals; where the signals within a differential pair must route together for their entire route.
5. Do not place vias between adjacent complementary clock traces and avoid any differential vias. Vias that are placed in one signal of a differential pair must be matched by a via in the complement signal within a differential pair.
6. At least one ground stitching via must be placed within 30mils(0.762mm) from every signal transition via when ever they change signal layers.
7. Any differential clock pair not being used must be left as no connects
8. Refer to details covered in the "Stack-Up and PCB Considerations" chapter for Trace Impedance, Differential Spacing, Group Spacing, and Isolation Spacing requirements

12.2.5 Single-Ended LPC Clock Routing Guidelines

- Single-Ended Clock Signals:
 - CLKOUT_LPC[1:0]

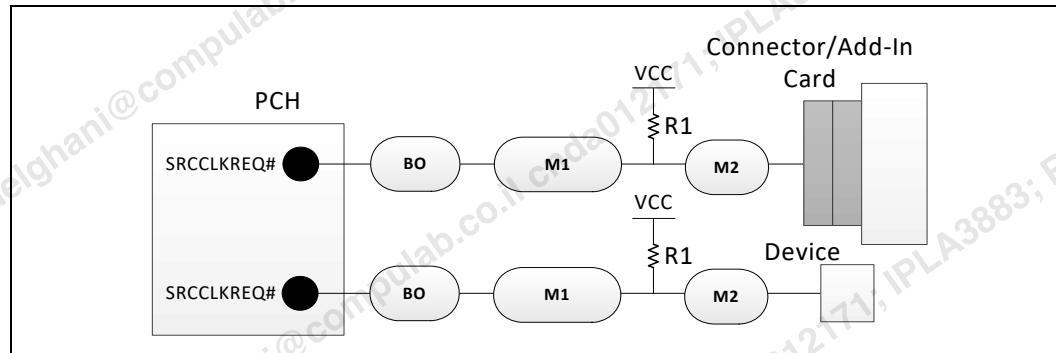
Note:

Refer Chapter 29, “Low Pin Count (LPC) Interface Design Guidelines” for the Single-Ended LPC Clock Routing Guidelines

12.3 Platform Clock Associated Signal Guidelines

12.3.1 SRC Clock Request Routing Guidelines

- Serial Reference Clock Request Signals:
 - SRCCCLKREQ#[15:0]

**Figure 12-7. SRC Request Signal Topology****Table 12-6. SRC Request Signal Routing Guidelines**

Parameter	Segment	Stack-up	Rule
Reference Plane	BO, M1, M2	MS/SL/DSL	Ground
Max Segment Length	BO	MS/SL/DSL	100mils(2.54mm)
	M2	MS/SL/DSL	100mils(2.54mm)
Total Motherboard Length	PCH-2-Connector (BO+M1+M2)	MS/SL/DSL	10000mils(254mm)
	PCH-2-Device (BO+M1+M2)	MS/SL/DSL	12000mils(304.8mm)
Resistor (R1)			10k Ohm ±10%
Max Transition Via Count			Refer Note
Note:			
1. BO = Motherboard Break Out Segment, M = Motherboard Main Segments			
2. MS = Micro-Strip, SL = Strip-Line, DSL = Dual Strip-Line			
3. Ground referencing is preferred. However, single ended clocks can be routed referenced to other planes through the use of stitching capacitors to provide decoupling where the signal crosses planes			
4. At least one ground stitching via must be placed within 30mils(0.762mm) from every signal transition via when ever they change signal layers.			
5. There are no Max Transition Via Count restrictions but it is recommended to minimize the number of via layer transitions on the SRCCCLKREQ# signals.			
6. The 10k Ohm pull-up must be pulled up on the rail that the corresponding SRCCCLKREQ# pin resides in. PCIe* devices that support the clock request protocol and are powered on only in the S0 state should use core well (S0) powered signals that can be mapped to output any PCI Express* clock as appropriate			
7. The SRCCCLKREQ#[15:0] signals can be configured to map to any of the PCH-H PCI Express* Root Ports			
8. SRCCCLKREQ#[15:0] to CLKOUT_PCIE_P/N[15:0] Mapping Requirements			
— SRCCCLKREQ#[7:0] signals can be mapped to any of the CLKOUT_PCIE_P/N[7:0] differential clock pairs			
— SRCCCLKREQ#[15:8] signals can be mapped to any of the CLKOUT_PCIE_P/N[15:8] differential clock pairs			
9. Any un-used SRCCCLKREQ# signal must be left as no connects			
10. Refer to details covered in the "Stack-Up and PCB Considerations" chapter for Trace Impedance, Differential Spacing, Group Spacing, and Isolation Spacing requirements			

12.3.2 24 MHz Input Clock Routing Guidelines

- 24 MHz Signals:
 - XTAL_IN
 - XTAL_Out
 - CLKIN_XTAL

Notes:



1. All CFL processor based platforms are required to provide a 24 MHz input to the PCH to enable the PCH to generate all of its internal reference clocks and all of the single-ended and differential platform clock outputs. Refer [Figure 12-2, "PCH XTAL Input Configuration Diagram"](#) for the 24 MHz input configuration options.
2. It is strongly recommended that customers designing a Platform pay special attention and follow all of the XTAL_IN/XTAL_OUT/CLKIN_XTAL routing guidelines. The crystal, components, and their XTAL_IN/XTAL_OUT/CLKIN_XTAL signals are very sensitive to board noise and care must be taken when routing and placing these components and signals on the motherboard to provide shielding from any noisy signals or power planes near the components and traces. The details covered in this section provide the guidelines needed to ensure the best environment for these components and signals. Any deviation from these guidelines could result in some platform clock instabilities.

12.3.2.1 24 MHz Crystal External Load Capacitor Requirements

The 24 MHz crystal is physically tuned to operate within the specified frequency range and ppm tolerance with a certain expected capacitive load present. The expected external capacitive load to be used (C_e) consists of the crystal capacitive load plus the pin and trace capacitances. The external load capacitors are important to minimize frequency variations from the crystal by compensating for variable PCB factors related to pin and trace capacitance. Care must be exercised in the selection of the external load capacitors to present the expected capacitive load specified for the crystal in use on the platform.

The appropriate capacitor value for the platform may be determined using the following formula:

$$C_e = 2 * [C_L - (C_s + C_i)], \text{ where:}$$

- C_e = External Load Capacitor Value = $C_{e1} = C_{e2}$
- C_L = Specified Crystal Capacitive Load = 12pF
 - Found in crystal component data sheet
- C_s = Board Trace Capacitance = < 3pF
 - Includes crystal pad capacitance
- C_i = PCH Pin Capacitance = < 2 to 3pF

Due to vendor variation in crystal characteristics, layout variations and PCB trace capacitance differences, the above calculation should be performed for each design to determine the precise value of C_e that is optimal for the particular platform.

12.3.2.2 24 MHz Crystal Specification Requirements

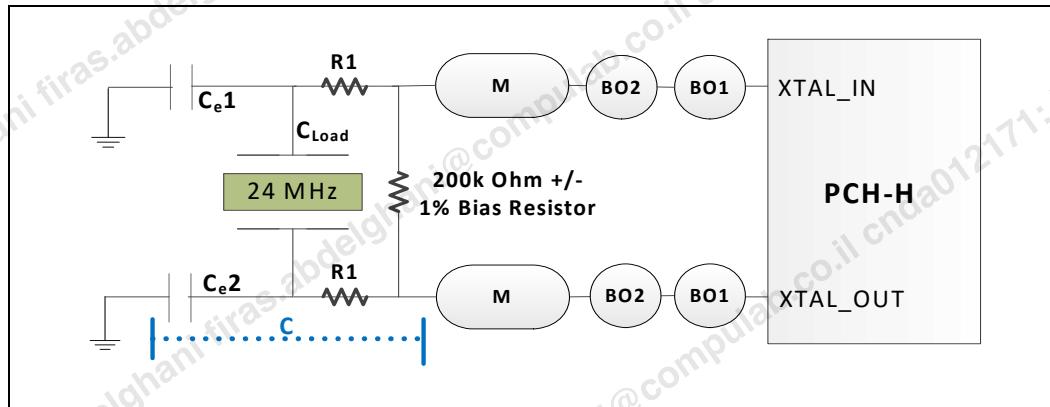
Table 12-7. 24 MHz Crystal Specifications (Sheet 1 of 2)

Parameter	Values	Units	Max/Min Range
Frequency	24	MHz	
Frequency Tolerance	≤ 100	PPM	
Duty Cycle Variation	$+/- 5$	%	
Operating Temperature	-40 to 85	°C	
Series Resistance	≤ 30	Ω	

Table 12-7. 24 MHz Crystal Specifications (Sheet 2 of 2)

Parameter	Values	Units	Max/Min Range
Aging	± 3	PPM	
Note:			
1. Customers should verify that the vendor's published specifications in the component data sheet meet the required conditions for frequency, frequency tolerance, temperature, oscillation mode and load capacitance as specified in the respective data sheet.			
2. Perform conformance testing and EMC (FCC and EN) testing in real systems			
3. Independently measure the component's electrical parameters in real systems. Measure frequency at a test output to avoid test probe loading effects. Check that the measured behavior is consistent from sample to sample and that measurements meet the published specifications. For crystals, it is also important to examine startup behavior while varying system voltage and temperature.			

12.3.2.3 PCH-H Platform Crystal XTAL_IN/OUT Routing Guidelines

Figure 12-8. PCH-H Platform Crystal XTAL_IN/OUT Topology**Table 12-8. PCH-H Platform Crystal XTAL_IN/OUT Routing Guidelines (Sheet 1 of 2)**

Parameter	Segment	Stack-up	Rule
Reference Plane	BO1, BO2, M	MS/SL/DSL	Ground
Signal Placement	BO1, BO2, M	SL/DSL	<ul style="list-style-type: none"> The XTAL_IN/OUT signals must be routed on inner layers (SL or DSL) where they must be ground referenced with solid ground floods on both sides <ul style="list-style-type: none"> If needed the BO1+BO2 segment may be routed on the same single micro-strip layer as the XTAL component
Single Ended Trace Impedance	BO1, BO2, M	MS/SL/DSL	50 Ohms
Min Group Spacing	BO1, BO2	MS/SL/DSL	Signal to Via Void = 5 mils Signal to Signal = 8 mils
	M	MS/SL/DSL	Signal to Via Void = 15 mils Signal to Signal = 15 mils



Table 12-8. PCH-H Platform Crystal XTAL_IN/OUT Routing Guidelines (Sheet 2 of 2)

Parameter	Segment	Stack-up	Rule
Min Isolation Spacing	BO1 (If Needed)	MS/SL/DSL	<ul style="list-style-type: none">XTAL_IN/OUT to non-HSIO Via Void = 8 milsXTAL_IN/OUT to non-HSIO Signal = 8 milsXTAL_IN/OUT to HSIO Via Void = 20 milsXTAL_IN/OUT to HSIO Signal = 20 mils for a max length of 30 mils<ul style="list-style-type: none">Optimized spacing value = 30 mils min
	BO2	MS/SL/DSL	<ul style="list-style-type: none">XTAL_IN/OUT to non-HSIO Via Void = 8 milsXTAL_IN/OUT to non-HSIO Signal = 8 milsXTAL_IN/OUT to HSIO Via Void = 50 milsXTAL_IN/OUT to HSIO Signal = 50 mils for a max length of (100 mils - Break-Out #1 Length)
	M	MS/SL/DSL	<ul style="list-style-type: none">XTAL_IN/OUT to non-HSIO Via Void = 20 milsXTAL_IN/OUT to non-HSIO Signal = 20 milsXTAL_IN/OUT to HSIO Via Void = 70 milsXTAL_IN/OUT to HSIO Signal = 70 mils<ul style="list-style-type: none">Optimized spacing value = 100 mils min
Max Segment Length	BO1+BO2	MS/SL/DSL	100 mils
Max Total Length	BO1+BO2+M	MS/SL/DSL	1000 mils
Length Matching	BO1+BO2+M	MS/SL/DSL	±100 mils
Max Transition Via Count			2
External Load Capacitor (Ce1,Ce2)			18pF +/-10%
R1			0 Ohms
GND Shield			<ul style="list-style-type: none">4 mil minimum wide GND shield trace placed evenly between XTAL_IN/OUT to any adjacent VIA Void, power flood, or Signal. If possible this GND shield should also extend around the XTAL crystal components.GND stitching vias must be placed throughout the GND shield where possible to stitch the GND Shield to groundRefer GND shield example in Figure 12-10.

Note:

- BO = Motherboard Break Out Segment, M = Motherboard Main Segments
- MS = Micro-Strip, SL = Strip-Line, DSL = Dual Strip-Line, HSIO = High Speed I/O
- At least one ground stitching via must be placed within 30mils(0.762mm) from every signal transition via when ever they change signal layers.
- The oscillator signals are very sensitive to board noise. As a result it is strongly recommended not to route or place any inductive components or high-speed switching signals directly below or above the XTAL_IN/XTAL_OUT signals and the Crystal; including its components (resistors and capacitors).
- Since these signals are single-ended designers must not route them over or across any voids and they must not route them over any split planes or different reference planes.
- The documented Ce1/Ce2 external load capacitance value was calculated using the formula in [Section 12.3.2.1](#) and is based off the customer reference design configuration, stack-up, and the crystal characteristics that its using which is defined in the platform design guide. Due to vendor variation in crystal characteristics, layout variations, and PCB trace capacitance differences the formula should be used for each design to determine the value of Ce1/Ce2 that is optimal for the particular platform.
- If the XTAL_IN or XTAL_OUT signals are routed on inner PCB layers (DSL or SL) they must be ground referenced with solid ground floods on both sides.
- The crystal input clock can be sensitive to RF power from nearby radios. For more details reference the "Crystal (Xtal) RF Immunity" chapter

12.3.3 XCLK_BIASREF Guidelines

- BIAS Reference Signal:

— XCLK_BIASREF

Figure 12-9. XCLK Bias Reference Topology

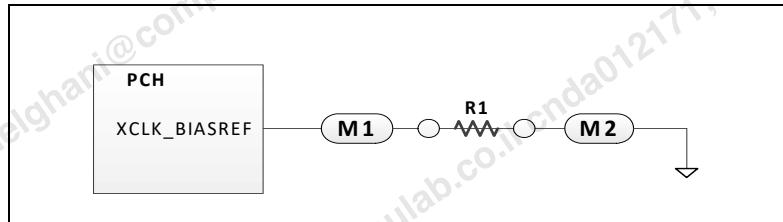


Table 12-9. XCLK Bias Reference Routing Guideline

Parameter	Segment	Stack-up	Rule
Reference Plane	M1, M2	MS/SL/DSL	Ground
Single Ended Trace Impedance	M1, M2	MS/SL/DSL	Refer Note
Max Total Length	M1+M2	MS/SL/DSL	1000mils(25.4mm)
Resistor (R1)			60 Ohm $\pm 1.0\%$
Max Transition Via Count			2

Note:

1. M = Motherboard Main Segments
2. MS = Micro-Strip, SL = Strip-Line, DSL = Dual Strip-Line
3. At least one ground stitching via must be placed within 30mils(0.762mm) from every signal transition via when ever they change signal layers.
4. It is strongly recommended to route the XCLK_BIASREF signal as short as possible where the external series resistor (R1) is placed within 1000 mils from the PCH.
5. No Single Ended Trace Impedance target is identified. Requires low DC resistance routing < 0.5Ω where the max capacitance of the overall net must be <5pf as any extra capacitance can affect pin stability.
6. If desired add a VSS shield, at least 4mil(0.1016mm) wide, between the XCLK signal to any adjacent signal or power flood. If VSS shielding is implemented, then VSS stitching vias must be placed throughout the VSS shield where possible to stitch the VSS Shield to ground. Refer complete details covered in [Figure 12-10](#). Note that the preferred method of isolating the XCLK signals is to follow the Min Isolation Spacing rules.

Figure 12-10. XCLK Bias Reference VSS Shield Spacing Recommendations

§ §



13 Real Time Clock (RTC) Design Guidelines

13.1 Real Time Clock (RTC) Design Guidelines

The PCH contains a real time clock (RTC) with 256 bytes of battery-backed SRAM. The internal RTC module provides two key functions: keeping date and time and storing system data in its RAM when the system is powered down.

The PCH RTC module requires an external oscillating source 32.768KHz connected on the RTCX1 and RTCX2 balls. Figure below shows the external circuitry that comprises the oscillator of PCH RTC.

The PCH uses a crystal circuit to generate a low-swing 32 kHz input sine wave. This input is amplified and driven back to the crystal circuit via the RTCX2 signal. Internal to PCH, the RTCX1 signal is amplified to drive internal logic.

Table 13-1. Reference Specification

Title	Location
Design Considerations for Platforms Without a Coin Cell Battery - White Paper	RDC#549657
Intel® I/O Controller Hub (Intel® ICH)/ Platform Controller Hub (PCH) Family Real Time Clock (RTC) Electrical, Mechanical, and Thermal Specification (EMTS) - AP-728	http://www.intel.com/content/www/us/en/chipsets/ich-family-real-time-clock-accuracy-considerations-note.html?wapkw=rtc

13.1.1 RTC Signal Description

Signals	Description
RTCX1	Crystal Input 1
RTCX2	Crystal Input 2
SUSCLK	RTC Clock
RTCRST#	RTC Reset
SRTCRST#	Secured RTC Reset

13.1.2 RTC Topology Guideline

13.1.2.1 VCCRTC External Circuit

On CFL, the VCCRTC max voltage is being reduced to minimize leakage on the ESD diodes and prevent RTC oscillator problems. Whether VCCRTC is sourced from Vbatt in G3 or VCCDSW_3p3 in Non-G3 state, platform designers must ensure the effective voltage at VCCRTC does not exceed 3.46V.



13.1.2.2 General RTC Layout Considerations

Since the RTC circuit is very sensitive and requires highly accurate oscillation, reasonable care must be taken during layout and routing of the RTC circuit. Figure and table below provides some general length guidelines for the RTC crystal circuit.

For additional information about RTC Layout Considerations, refer to *Intel® I/O Controller Hub (Intel® ICH)/Platform Controller Hub (PCH) Family Real Time Clock (RTC) Electrical, Mechanical, and Thermal Specification (EMTS) - AP-728* for details layout consideration and fine tuning.

Figure 13-1. RTC Crystal Input Topology

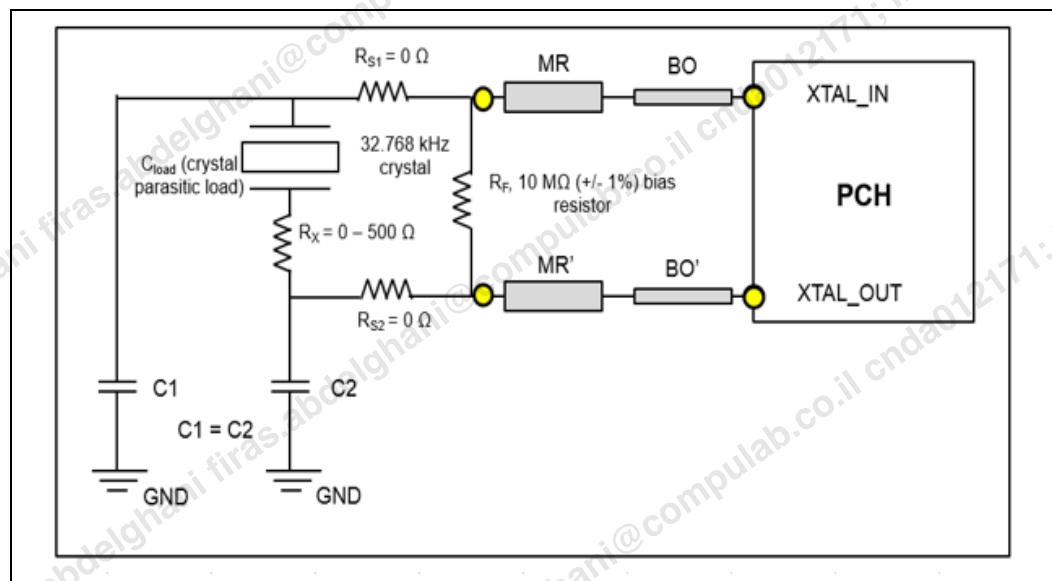


Table 13-2. RTC Routing Guidelines

Parameter	Segment / Signal Name	Stack up (MS/SL/DSL)	Units	Recommendation
Maximum Length	BO	MS/SL/DSL	mils	500
Maximum Length	MR	MS/SL/DSL	mils	500
Maximum Length	BO+MR	MS/SL/DSL	mils	1000
XTAL_IN and XTAL_OUT length matching maximum	NA	MS/SL/DSL	mils	50
External Capacitors ⁷	C1, C2	MS	pF	18+/-10%
Resistor	RF	MS	MΩ	10

Notes:

7. The exact capacitor values for C1 and C2 must be based on the crystal maker recommendations. Typical values for C1 and C2 are 18 pF, based on crystal load of 12.5 pF.

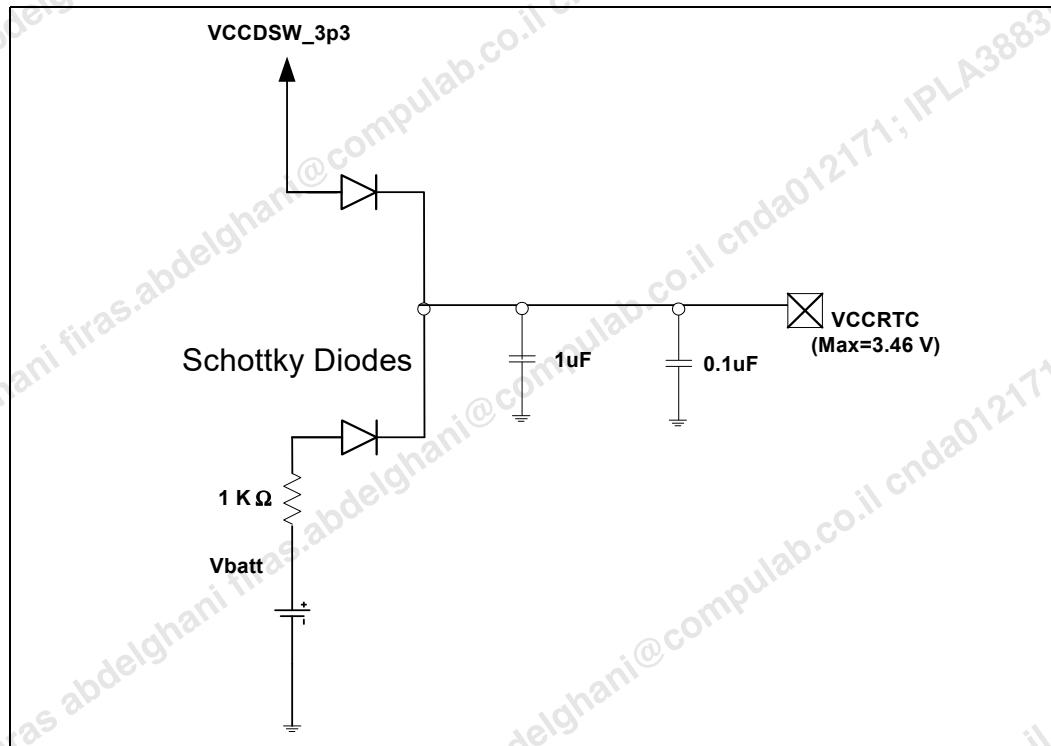
13.1.2.3 RTC External Battery Connection

The RTC requires an external battery connection to maintain its functionality and its RAM while PCH is not powered by the system.

The voltage of the battery can affect the RTC accuracy. In general, when the battery voltage decays, the RTC accuracy also decreases.

The battery must be connected to PCH using an isolation Schottky diode circuit. The Schottky diode circuit allows PCH RTC well to be powered by the battery when the system power is not available, but by the system power when it is available. To do this, the diodes are set to be reverse biased when the system power is not available. The following figure is an example of a diode circuit that is used.

Figure 13-2. Schottky Diode Circuit to Connect RTC External Battery



A standby power supply should be used in a mobile system to provide continuous power to the RTC when available, which will significantly increase the RTC battery life and thereby the RTC accuracy.

Using a rechargeable coin battery or a capacitor with a short projected discharged time can increase the risk of:

- an un-provisioned Intel® Active Management Technology (Intel® AMT)
- unusable anti-replay blobs
- Intel® Management Engine (Intel® ME) file system corruption

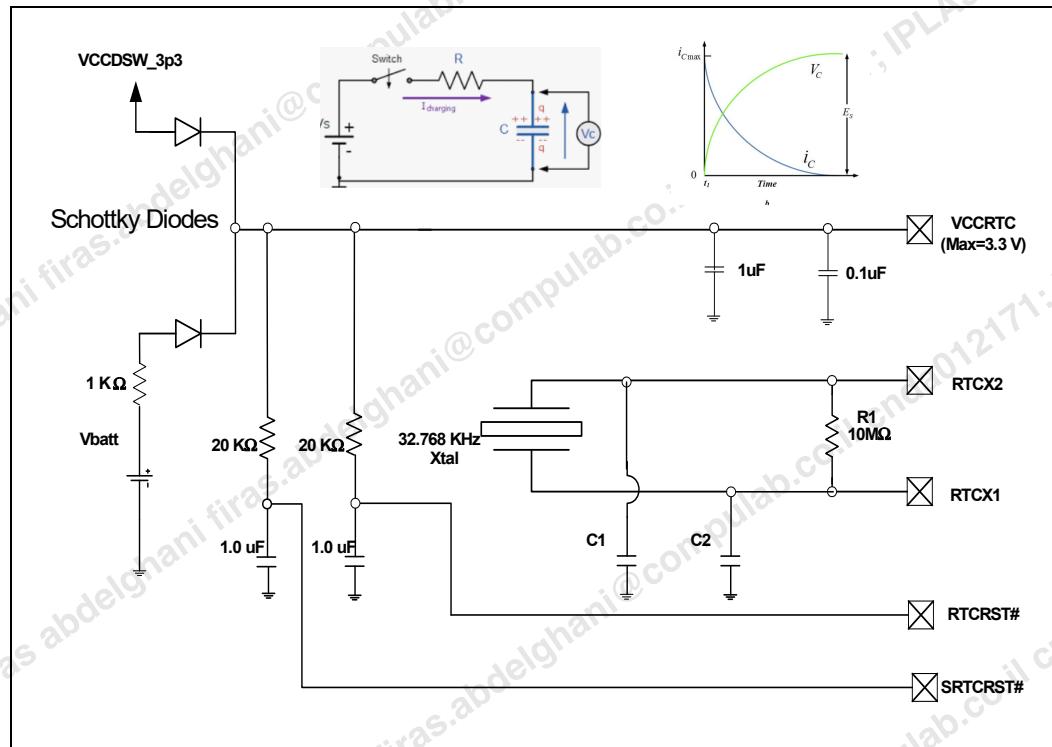
The first two cases are recoverable: Intel® Active Management Technology (Intel® AMT) can be re-provisioned, and applications using the anti-replay-blobs can be re-enrolled. The third case, the corruption of the Intel® Management Engine (Intel® ME) file system, is irretrievable, but has a very low probability of occurring even when a full discharge occurs.

13.1.2.4 RTC Coin-cell less implementation

Modern implementation of the RTC can also be designed without a coin-cell battery. Details on this implementation is available in the *Design Considerations for Platforms Without a Coin Cell Battery - White Paper*.

13.1.3 RTC External RTCRST#/SRTCRST# Circuit

Figure 13-3. RTCRST#/SRTCRST# External Circuit for PCH RTC



The RTCRST# signal is used to reset the RTC well.

Note:

RTC RST# should be generated from VBAT with a RC delay of 18–25 ms.

When RTCRST# is asserted, bit 2 (RTC_PWR_STS) in the GEN_PMCON_3 (General PM Configuration 3) register is set to 1, and remains set until software clears it. As a result of this, when the system boots, the BIOS knows that the RTC battery has been removed.

The RTCRST# signal may also be used to detect a low battery voltage. RTCRST# will be asserted during a power up from G3 state if the battery voltage is below 2V. This will set the RTC_PWR_STS bit as described above. If desired, BIOS may request that the user replace the battery.

This RTCRST# circuit is combined with the diode circuit (refer figure above) whose purpose is to allow the RTC well to be powered by the battery when the system power is not available. The above figure is an example of this circuitry that is used in conjunction with the external diode circuit.



13.1.4

RTC External SRTCRST# Circuit

The SRTCRST# signal is used to reset the RTC registers used for the Intel® Management Engine (Intel® ME) when the on board battery is changed. The external capacitor and the external resistor between SRTCRST# and VccRTC were selected to create an RC time delay, such that RTCRST# will go high some time after the battery voltage is valid. The RC time delay should be in the range of 18–25 ms. There must not be a jumper for SRTCRST# pin. The SRTCRST# does not impact the implementation of CMOS clearing. Refer to [Figure 13-3](#) external circuit for PCH RTC.

Notes:

- RC time delay for SRTCRST# should be the same as RC delay for RTRST#.
- RTRST# and SRTCRST# cannot be shorted together.

13.1.4.1

RTC-Well Input Strap Requirements

All RTC-well inputs (RSMRST#, RTRST#, SRTCRST#, INTRUDER#, PCH_PWROK, DSW_PWROK) must be either pulled up to VccRTC or pulled down to ground while in the G3 state. RTRST#, when configured as shown in [Figure 13-3](#) meets this requirement. RSMRST# should have a weak external pull-down to ground, and INTRUDER# should have a weak external pull-up to VccRTC. This will prevent these nodes from floating in G3, and correspondingly will prevent ICCRTC leakage that can cause excessive coin-cell drain. The PCH_PWROK and DSW_PWROK input signal should also be configured with an external weak pull-down.

13.1.4.2

RTC Component Selection Guidelines

13.1.4.2.1

External Capacitors

To maintain the RTC accuracy, the external capacitor values C1 and C2 should be chosen to provide the manufacturer's specified load capacitance (C_{load}) for the crystal when combined with the parasitic capacitance of the trace, socket (if used), and package.

$$C_{load} = \frac{[(C_1 + C_{in1} + C_{trace1}) \cdot (C_2 + C_{in2} + C_{trace2})]}{[(C_1 + C_{in1} + C_{trace1}) + (C_2 + C_{in2} + C_{trace2})]} + C_{parasitic}$$

For additional information about the External Capacitors, refer to *Intel® I/O Controller Hub (Intel® ICH)/Platform Controller Hub (PCH) Family Real Time Clock (RTC) Electrical, Mechanical, and Thermal Specification (EMTS) - AP-728* for details on fine tuning.



14 Asynchronous and Sideband Signals Design Guidelines

This chapter describes the topologies and layout recommendations for the asynchronous signals. Refer to the Coffee Lake processor EDS for more details.

14.1 Signal Descriptions

14.1.1 Signal Groups

Table 14-1. Asynchronous and Sideband Legacy Signal Group (Sheet 1 of 2)

Signal Name	Description
PROCHOT#	PROCHOT# goes active when the Coffee Lake processor temperature monitoring sensor(s) detects that the Coffee Lake processor has reached its maximum safe operating temperature. This indicates that the Coffee Lake processor Thermal Control Circuit (TCC) has been activated, if enabled. This signal can also be driven to the Coffee Lake processor to activate the TCC.
CATERR#	This signal indicates that the system has experienced a catastrophic error and cannot continue to operate. The Coffee Lake processor will set this for non-recoverable machine check errors or other unrecoverable internal errors. On the Coffee Lake processor, CATERR# is used for signaling the following types of errors: Legacy MCERRs - CATERR# is asserted for 16 BCLKs. Legacy IERRs - CATERR# remains asserted until warm or cold reset.
PROCPWRGD	Coffee Lake processor input signal Processor Power Good: The processor requires this input signal to be a clean indication that the VCC and VDDQ power supplies and BCLK are stable and within specifications. This requirement applies regardless of the S-state of the processor. 'Clean' implies that the signal will remain low (capable of sinking leakage current), without glitches, from the time that the power supplies are turned on until they come within specification. The signal must then transition monotonically to a high state.
VCCST_PWRGD	The Coffee Lake processor requires this input signal to be clean indicating that the VCC_ST and VDDQ power supplies. This requirement applies, regardless of the S-state of the Coffee Lake processor. 'Clean' implies that the signal will remain low (capable of sinking leakage current), without glitches, from the time that the power supplies are turned on until they come within specification. The signal must then transition monotonically to a high state. This is connected to the Coffee Lake processor VCCST_PWRGD signal.
THERMTRIP#	Coffee Lake processor output signal: Processor Asserted by the Coffee Lake processor to indicate a thermal trip event which may cause processor sever damage, causing the Coffee Lake processor to transition to an S5 state.
RESET#	Platform Reset signal is driven by PCH to the Coffee Lake processor.
PECI	The PECI interface is a controlled and reliable one-wire, bi-directional signal which is used to communicate the temperature of the Coffee Lake processor digital thermometer to the PECI host controller or to monitor and control Coffee Lake processor information such as energy, power limits, status, and DDR temperature.
BPM#[3:0]	Coffee Lake processor bi-directional signal that indicate the status of breakpoints and programmable counters used for monitoring Coffee Lake processor performance
PM_SYNC	Coffee Lake processor input signal Power Management Sync: A sideband signal to communicate power management status from the PCH to the processor.
PM_DOWN	Coffee Lake processor output signal Power Management Down: A Sideband to PCH. Indicates processor wake up event.
PROC_TRIGIN	Coffee Lake processor input signal: A Sideband to PCH.
PROC_TRIGOUT	Coffee Lake processor output signal: A Sideband to PCH.

**Table 14-1. Asynchronous and Sideband Legacy Signal Group (Sheet 2 of 2)**

Signal Name	Description
SVID: VIDSOUT VIDSCK VIDALERT#	VIDALERT#, VIDSCLK, and VIDSCLK comprise a three signal serial synchronous interface (SVID) used to transfer power management information between the Coffee Lake processor and the voltage regulator controllers. Alert signal must be routed between Clk and Data signals to minimize Cross-Talk.

14.2 Topology Guidelines

This section describes topologies and layout recommendations for the legacy signals. Although these signals toggle with relatively low frequency, most of them have very high-edge rates.

Warning:

Inappropriate routing or lack of termination can seriously decrease signal quality and lead to electrical specification violations and even logical system failures. The following guidelines apply to all legacy signals described in this section.

- Watch for termination recommendations. If any of the signals that require motherboard termination are pulled-up to a voltage higher than VCCST, the reliability and power consumption of the Coffee Lake processor may be affected. Therefore, it is very important to follow the recommended pull-up voltage for these signals.
- For Type 3 PCB, routing guidelines allow the asynchronous signals to be routed as either microstrip using $50 \Omega \pm 15\%$ characteristic trace impedance or stripline using $50 \Omega \pm 10\%$ characteristic trace impedance or orthogonal DSL (with only one layer of parallel routing, the routing on the second, adjacent layer, must be orthogonal to the first one) using $50 \Omega \pm 10\%$ characteristic trace impedance.
- For Type 4 PCB, routing guidelines allow the asynchronous signals to be routed as either microstrip using $50 \Omega \pm 15\%$ characteristic trace impedance or orthogonal dual - stripline using $50 \Omega \pm 12\%$ characteristic trace impedance.
- Changing reference plane is not recommended and may cause signal integrity degradation. In any case, if such routing cannot be avoided, use stitching vias and bypass capacitors between the reference planes near the layer transition.
- General trace spacing requirements (for 50Ω characteristic impedance traces) specified in the following table. W is trace width and S is the space between 2 adjacent traces.

Table 14-2. Asynchronous and Sideband Signal General Routing Guideline

Trace Type	Stack-up (MS/SL/DSL)	Units	Minimum Spacing (S)
Microstrip	MS	mils	12
Stripline	SL	mils	12
Dual-Stripline	DSL	mils	12
Microstrip PECL	MS ¹	mils	18
Microstrip SVID	MS ^{1,3}	mils	15

Notes:

- Parameters for SVID Bus and PECL microstrip routing only.
- The main route segments (M) of the asynchronous signals listed below are expected to follow the spacings mentioned in the table above while breakin (BI) and breakout (BO) segments are expected to have 4 mils spacing to adjacent signals.
- Additional spacing guidelines in [Section 14.2.13, "SVID Topology"](#).



14.2.1 PROCHOT# Topology

The signal can be driven either by the Coffee Lake processor, Embedded Controller (EC) or by VR. If connected from PROCHOT# to particular manufacturer temp sensor and not VR as described in the topology, such PROCHOT# connection must have the drive capabilities as defined in the future available VR specification.

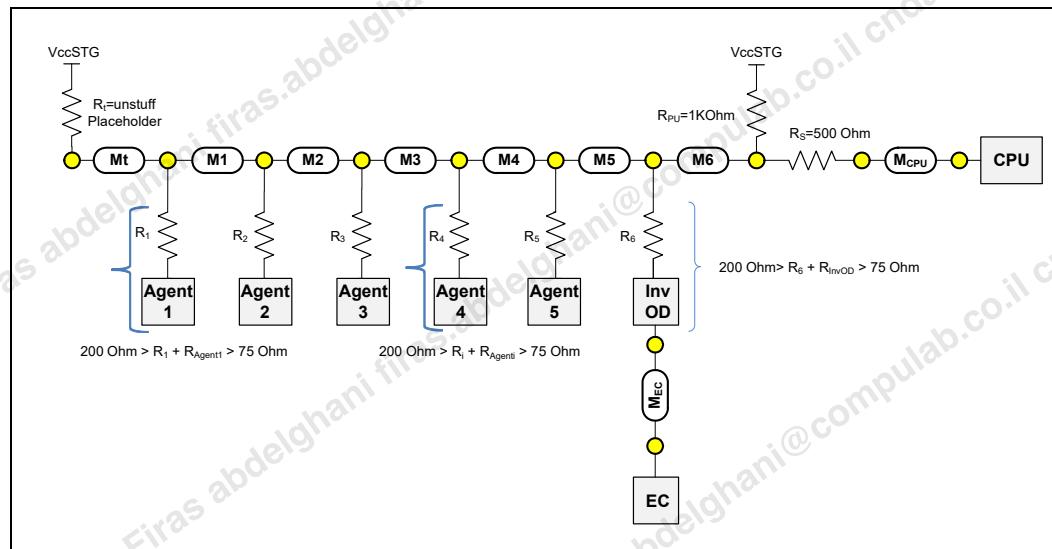
Consider the following:

1. PROCHOT# is capable of toggling hundreds of times per second to signal a hot temperature condition.
2. If PROCHOT# is not used, then it must be terminated with a $1\text{K}\Omega \pm 5\%$ pull-up resistor to VCCSTG.

The EC output DC levels are typically 0 V and 3.3 V, Coffee Lake processor input DC levels are 0 V and 1.0 V. Coffee Lake processor's high voltage level is lower than EC's high voltage level, therefore an onboard voltage level shifter is required. An inverting logic level shifter must be used. EC asserts PROCHOT# signal by driving high, the level shifter must invert it and drive the Coffee Lake processor side PROCHOT# low.

Note:

The Topology demonstrated is designed to be unidirectional, the processor is the receiver.



- An Agent is any (OD) driver that is connected to the PROCHOT# signal, for example VR.
- R1-6 series resistors are needed to keep the PROCHOT# signal at safe level (reduce Under-shoot) if an Agent and/or Inv OD pull-down resistor is too low (driver is too strong). The total pull-down resistance of each agent should be between 75 and 200 Ω . Total pull-down resistance is defined as the sum of internal pull-down resistance of the agent and the series resistor Ri
- Examples:
 - If internal pull-down resistor of Agent1 is 75 Ω , no additional (on board.) series resistor is needed, R1 can be omitted.

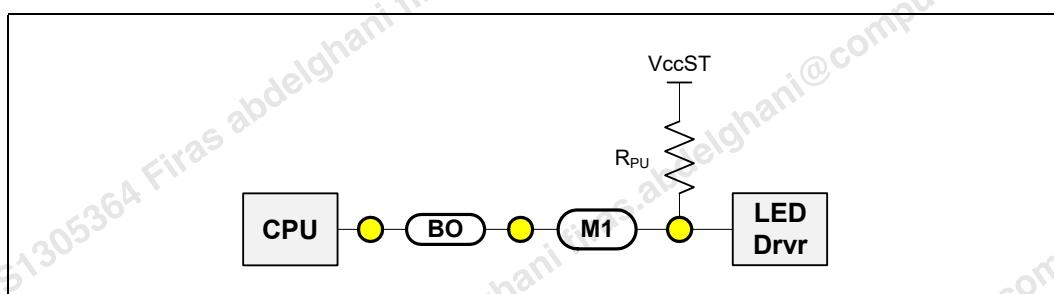
- If internal pull-down resistor of Agent2 is $15\ \Omega$, additional (on board) series resistor is needed to increase the total pull-down resistance of Agent2, $60 < R_2 < 185$ (R_2 can be $70\ \Omega$).
- The same applies to the Inv OD driver of the EC.

Table 14-3. PROCHOT# Routing Guidelines

Parameter	Segment	Stack-up (MS/ SL/DSL)	Units	Routing Recommendation
VCCSTG	NA	NA	V	1.0
M1,2,3,4,5	Mi	MS/SL/DSL	inches	<3
M6	Mi	MS/SL/DSL	inches	1-11
M _{CPU}	M _{CPU}	MS/SL/DSL	inches	0.3-1.5
Mt	Mt	MS/SL/DSL	mils	<0.3
Main route (M1+M2+M3+M4+M5+M6+MCPU)	M	MS/SL/DSL	inches	1-12
Resistor Value ($\pm 5\%$)	R _{PU}	NA	Ω	1000
Resistor Value ($\pm 5\%$)	R _S	NA	Ω	500
Resistor Value ($\pm 5\%$)	R _i +R _{Agenti}	NA	Ω	75-200
Resistor Value ($\pm 5\%$)	R ₆ +R _{INVOD}	NA	Ω	75-200
Notes:				
1. Add DB (Dog Bone) only as needed as MS. 2. All segments are $50\ \Omega$ and vias are optional.				

14.2.2 CATERR# Topology

CATERR# indicates system has experienced a catastrophic error and cannot continue to operate. The Coffee Lake processor will set this for non-recoverable machine check errors and other internal unrecoverable errors. CATERR# is an asynchronous open drain driver signal with no on-die termination (ODT). This signal can be connected to a LED if desired. Also, this signal should have an exposed test point for easy debug access.

Figure 14-1. Routing Illustration for CATERR# Topology

Table 14-4. CATERR# Routing Guidelines

Parameter	Segment	Stack-up (MS/ SL/ DSL)	Units	Routing Recommendation
VCCST	NA	NA	V	1.0
Breakout Length Max	Mi	MS/SL/DSL	inches	<0.5
M1	M1	MS/SL/DSL	inches	<12

14.2.3 PROCWRGD Topology

Figure 14-2. Routing Illustration for PROCWRGD Topology

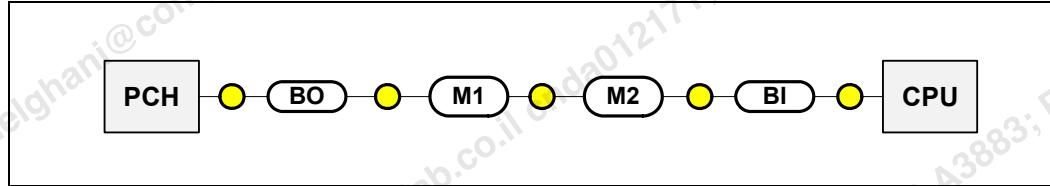


Table 14-5. PROCWRGD Routing Guidelines

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakout Length	BO	MS/SL/DSL	inches	<0.5
M1+M2	Mi	MS/SL/DSL	inches	1-11
Breakin Length Max.	BI	MS/SL/DSL	inches	<0.5
Notes:				
1. Add DB (Dog Bone) only as needed as MS. 2. All segments are 50 Ω and vias are optional.				

14.2.4 VCCST_PWRGOOD Topology

VCCST_PWRGD is a signal on the Coffee Lake processor that indicates both the VCCST power supply and VDDQ power supply are within voltage tolerance specifications.

When connecting to the XDP, a series R_{xdp} resistor of 1 kΩ is required to avoid VR to the Coffee Lake processor line overloading and to reduce signal integrity issues on the receiver. If the driver is CMOS it's supply must not exceed VccST

VCCST_PWRGD is only 1.0 V tolerant. If a dedicated driver is used to drive the VCCST supply, the VCCST_PWRGD should meet the requirements listed below:

- VCCST_PWRGD must be valid (stable at the right level) during all power states when there is a power applied to the VccST power supply.
- VCCST_PWRGD must be de-asserted before VDDQ or VCCST power level goes below voltage tolerance specification.

Figure 14-3. Routing Illustration for VCCST_PWRGOOD Topology

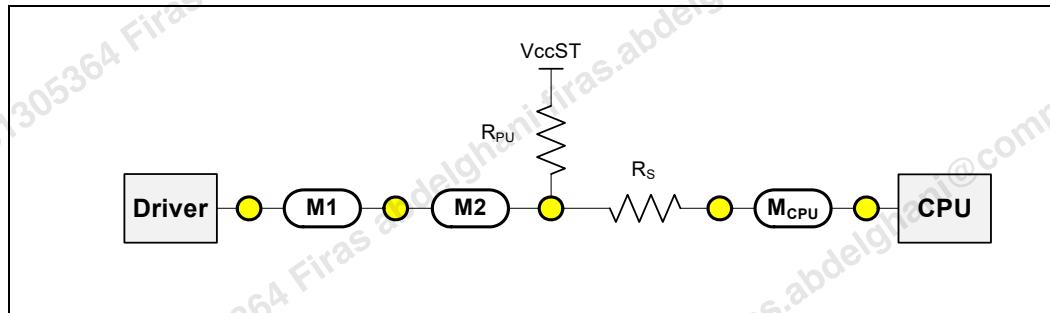


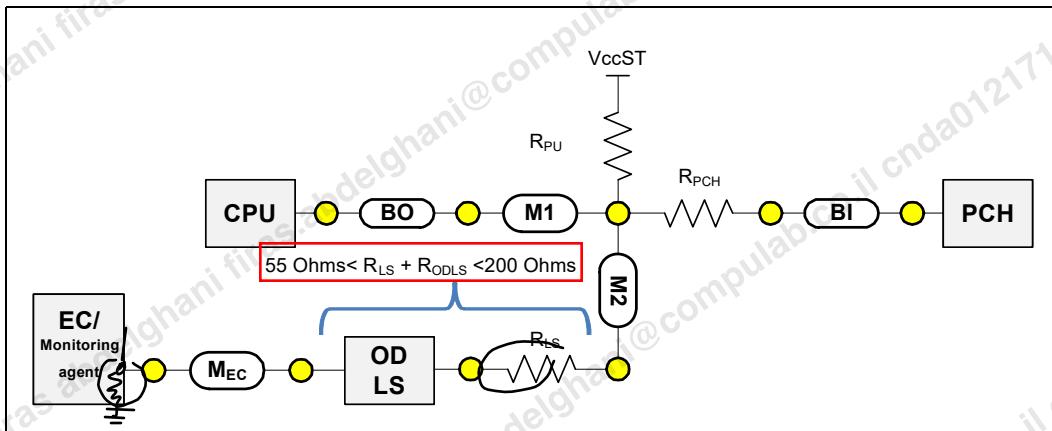
Table 14-6. VCCST_PWRGOOD Routing Guidelines

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	Routing Recommendation
Driver Ron	R _{Driver}	NA	Ω	<200
M1+M2	M _i	MS/SL/DSL	inches	1-11
M _{CPU}	M _{CPU}	MS/SL/DSL	inches	0.3-1.5
Resistor Value (\pm 5%)	R _S	NA	Ω	60
Resistor Value (\pm 5%)	R _{PU}	NA	Ω	1000

Notes:

1. All traces can be MS/SL/DSL as long as above guidelines are met.
2. Add DB (Dog Bone) only as needed on MS.
3. All segments are 50 Ω and vias are optional.

14.2.5 THERMTRIP# Topology

Figure 14-4. Routing Illustration for THERMTRIP# Topology


RLS series resistor is needed to keep the THERMTRIP# signal at safe level (reduce Under-shoot) if OD LS pull-down resistor is too low (driver is too strong). The total pull-down resistance of OD LS should be between 55 and 200 Ω. Total pull-down resistance is defined as the sum of internal pull-down resistance of the OD LS and the series resistor RLS. Examples:

- If internal pull-down resistor of OD LS is 55 Ω, no additional (on board) series resistor is needed => RLS can be omitted.
- If internal pull-down resistor of OD LS is 15 Ω, additional (on board) series resistor is needed to increase the total pull-down resistance of OD LS in range: $40 < R_{LS} < 185$, in order to meet the guideline: $55 < R_{LS} + R_{ODLS} < 200$.

Table 14-7. THERMTRIP# Routing Guidelines (Sheet 1 of 2)

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
VccST	NA	NA	V	1.0
Breakout Length	BO	MS/SL/DSL	inches	<0.5
M _{1,2}	M _i	MS/SL/DSL	inches	<10
M _{EC}	M _{EC}	MS/SL/DSL	inches	<10

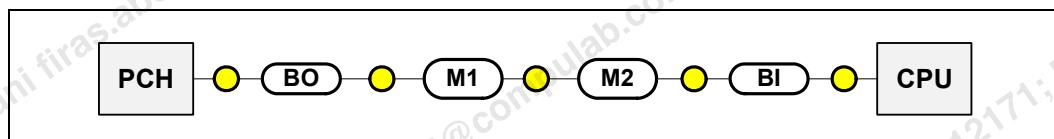
**Table 14-7. THERMTRIP# Routing Guidelines (Sheet 2 of 2)**

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakin Length	BI	MS/SL/DSL	inches	0.3-2
Resistor Value ($\pm 5\%$)	R _{PCH}	NA	Ω	620
Resistor Value ($\pm 5\%$)	R _{PU}	NA	Ω	1000
Resistor Value ($\pm 5\%$)	R _{ODLS+R_{LS}}	NA	Ω	55-200

Notes:

1. THERMTRIP# should be connected to EC or any other monitoring agent.
2. Add DB (Dog Bone) only as needed on MS.
3. All segments are 50 Ω and vias are optional.

14.2.6 RESET# (PLTRST#) Topology

Figure 14-5. Routing Illustration for RESET# (PLTRST#) Topology**Table 14-8. RESET# Routing Guidelines**

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakout Length	BO	MS/SL/DSL	inches	<0.5
M1+M2	Mi	MS/SL/DSL	inches	1-11
Breakin Length Max.	BI	MS/SL/DSL	inches	<0.5

Notes:

1. Add DB (Dog Bone) only as needed as MS.
2. All segments are 50 Ω and vias are optional.

14.2.7 Platform Environmental Control Interface (PECI) Topology

The digital thermometer will be used to communicate Coffee Lake processor core temperature to the platform. Access to the digital thermometer is through the Platform Environmental Control Interface (PECI).

The PECI interface is a controlled and reliable one-wire bi-directional signal which is used to communicate the temperature of the Coffee Lake processor digital thermometer to the PECI host controller or to monitor and control the Coffee Lake processor information such as energy, power limits, status and DDR temperature. Refer to the Platform Environmental Control Interface (PECI) 3 Specification for more architectural details. Also, refer to the *Processor Platform Environment Control Interface Implementation Guide* for commands for firmware coding. If a different PECI topology is implemented or one of the agents does not meet the PECI 3 Specifications, a simulation must be performed to ensure adequate signal quality and maximal operating frequency.

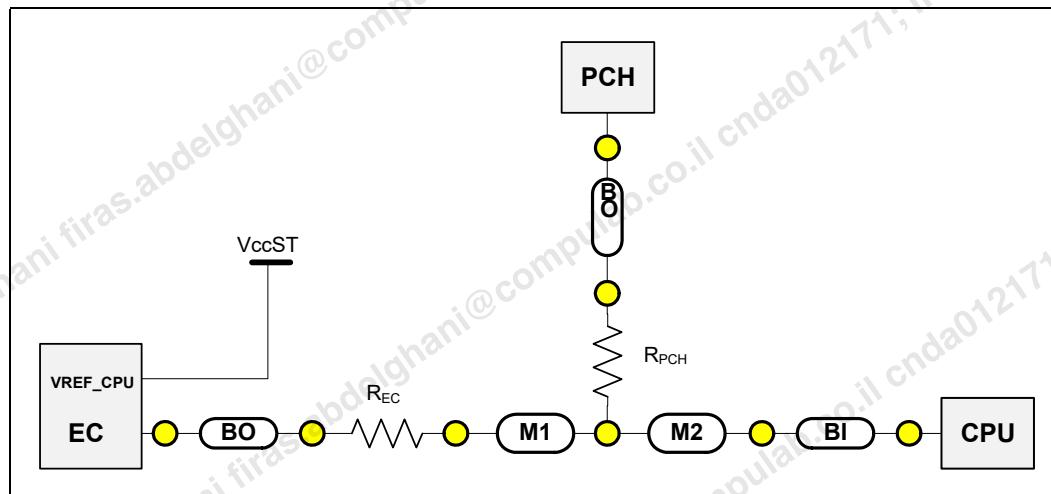
PECI spec has the bus in a L level when there are no transactions happening. The PECI host would normally drive the line H to start transactions, and the PECI clients (aka CPU) respond by over driving and keeping the line H when the Host tried to drive L. Only the PECI host drives the bus L, Clients can only pull up.

If there is no PECl host talking to the CPU and the pin is unused, put a 200-400Ω PD resistor to GND on the CPU pin to make sure it's statically L. It's not recommended to tie the CPU pin directly to GND.

Note: PECl routing guidelines were validated up to a host bandwidth of 1.6 Mbps.

Note: Intel Recommends using PECl Bus, If PECl is not used, it should be terminated to GND with 200-400Ω resistor.

Note: The VREF_PECI_EC voltage reference from the processor to the EC should be connected to VccST (PECl reference voltage)



PECl Routing Guidelines

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakout Length	BO	MS/SL/DSL	inches	<0.5
M1	M1	MS/SL/DSL	inches	3-12
M2	M2	MS/SL/DSL	inches	3-8
Breakin Length Max.	BI	MS/SL/DSL	inches	<0.5
Resistor Value (±5%)	R _{EC}	NA	Ω	33
Resistor Value (±5%)	R _{PCH}	NA	Ω	13

Notes:

1. Add DB (Dog Bone) only as needed as MS.
2. All segments are 50 Ohm and vias are optional.
3. If routed MS, PECl requires 18 mils (0.457 mm) spacing to other signals.
4. Adding another agent requires total change of topology.

- If PECl is not used on the CPU, then it should be terminated to GND with 200-400ohm resistor; the PCH-H PECl pin should be terminated to GND with a weak resistor if it is not connected to the CPU PECl pin, or it can be connected to the CPU PECl pin in order to share the same termination resistor.
- If PECl is used on the CPU, and C10 is supported, then PECl bus should also be connected to the PCH-H PECl pin (in addition to the PECl host) to correctly support C10.



- If PECl is used on the CPU, and C10 is not supported, then PECl bus is not required to be connected to the PCH-H PECl pin.

14.2.8 BPM#[3:0] Topology

Route the BPM#[3:0] signals point-to-point from the Coffee Lake processor pin to the XDP debug port connector. Adequate termination for these signals is provided within the I/O design of the Coffee Lake processor and on the ITP-XDP hardware. No external components are required. Length match these signals to within ± 360 mils (9.1 mm). Stubs on these nets should be limited to less than 1400 mils (35.5 mm) in length.

Figure 14-6. BPM#[3:0] Topology

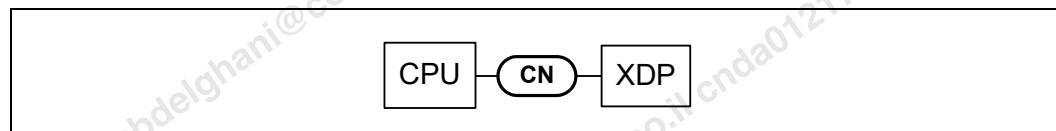


Table 14-9. BPM#[3:0] Routing Guidelines

Parameter	Segment	Routing Layer (MS/SL/DSL)	Units	Routing Recommendation
Connector Length	CN	MS/SL	inches	1 - 6

Note: All segments are 50 Ω and vias are optional.

14.2.9 PM_SYNC Topology

Figure 14-7. Routing Illustration for PM_SYNC Topology

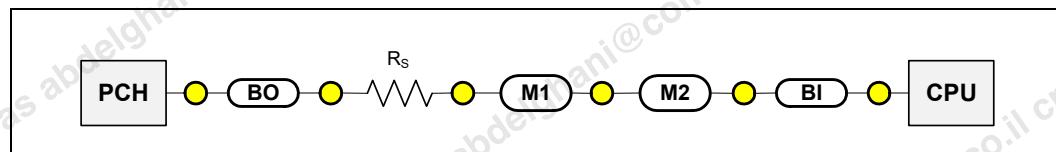


Table 14-10. PM_SYNC Routing Guidelines

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakout Length: Short route: M1 + M2 < 3" Long route: M1 + M2 > 3"	BO	MS/SL/DSL	inches	<0.2 <0.6
M1+M2: Short route Long route	Mi	MS/SL/DSL	inches	1-3 3-11
Breakin Length Max.	BI	MS/SL/DSL	inches	<0.5
Resistor Value ($\pm 5\%$)	Rs	NA	Ω	30

Note: All segments are 50 Ω and vias are optional.

14.2.10 PM_DOWN Topology

Figure 14-8. Routing Illustration for PM_DOWN Topology

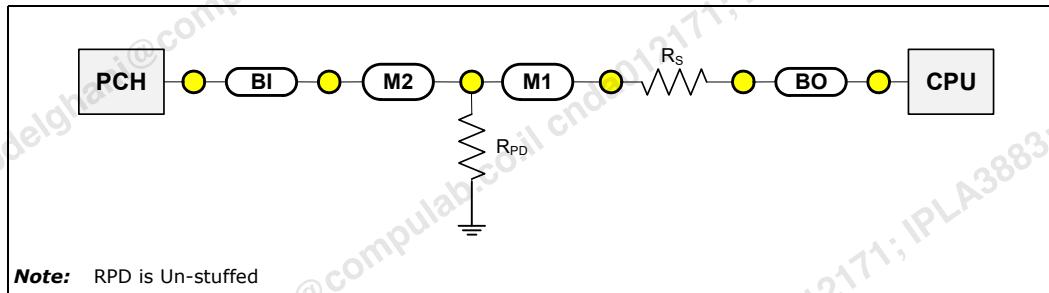


Table 14-11. PM_DOWN Routing Guidelines

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakout Length: Short route: M1 + M2 > 3" Long route: M1 + M2 < 3"	BO	MS/SL/DSL	inches	<0.2 <0.6
M1+M2: Short route Long route	MI	MS/SL/DSL	inches	1-3 3-11
Breakin Length Max.	BI	MS/SL/DSL	inches	<0.5
Resistor Value ($\pm 5\%$)	Rs	NA	Ω	20
Resistor Value ($\pm 5\%$)	R _{PD}	NA	Ω	Unstuffed

Note: All segments are 50 Ω and vias are optional.

14.2.11 PROC_TRIGIN Topology (PCH to Processor_TRIGIN)

Figure 14-9. Routing Illustration for PROC_TRIGIN Topology

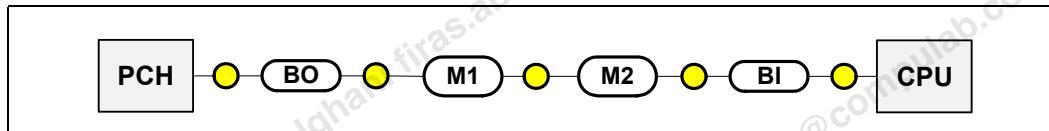


Table 14-12. PROC_TRIGIN Routing Guidelines

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakout Length	BO	MS/SL/DSL	inches	<0.5
M1+M2:	MI	MS/SL/DSL	inches	1-10
Breakin Length Max.	BI	MS/SL/DSL	inches	<0.5

Note: All segments are 50 Ω and vias are optional.



14.2.12 PROC_TRIGOUT Topology (Processor to PCH_TRIGIN)

Figure 14-10.Routing Illustration for PROC_TRIGOUT Topology

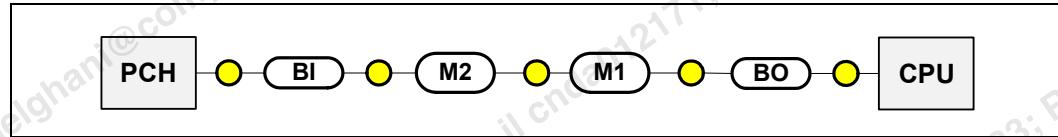


Table 14-13. PROC_TRIGOUT Routing Guidelines

Parameter	Segment	Stackup (MS/SL/DSL)	Units	Routing Recommendation
Breakout Length	BO	MS/SL/DSL	inches	<0.5
M1+M2	Mi	MS/SL/DSL	inches	1-10
Breakin Length Max.	BI	MS/SL/DSL	inches	<0.5

Note: All segments are $50\ \Omega$ and vias are optional.

14.2.13 SVID Topology

Figure 14-11.Routing Illustration for SVID Topology

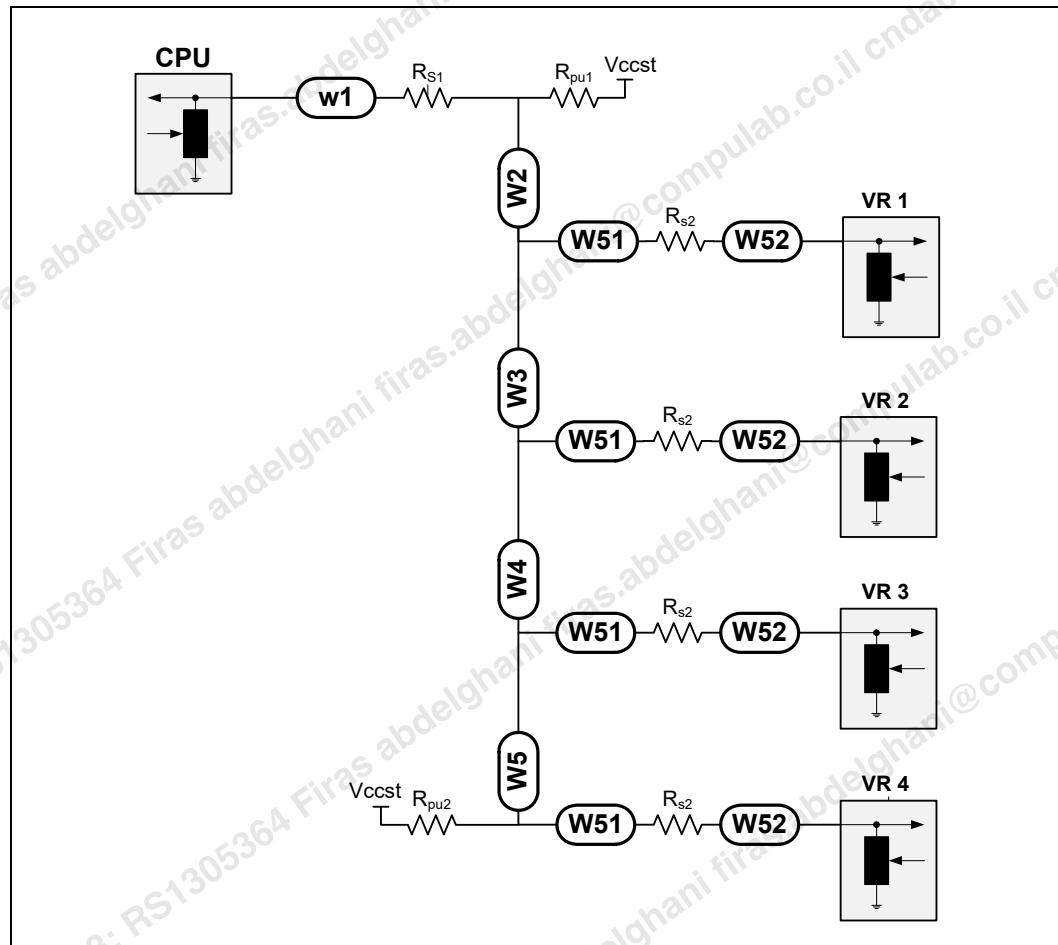




Figure 14-11 demonstrates Routing Illustration for SVID Topology, each trace from CPU to VR represents 3 signals: VIDSOUT, VIDSCK, VIDSAERT#.

Notes:

- If less than 4 VRs are used, remove the first devices from the topology. For example: if 3 VRs are used, remove VR1 from the topology.
- The total Length of Data and Clock (from CPU to each VR) must be equal (± 0.1 inch).
- Route the Alert signal between the Clock and the Data signals.

Table 14-14. SVID Bus Routing Guidelines

Signal	W1 [inches]	W2 [inches]	W3/4/5 [inches]	W2+W3+W4+W5 [inches]	W51 [inches]	W52 [inches]	R _{Pu1} [Ω]	R _{Pu2} [Ω]	R _{S1} [Ω]	R _{S2} [Ω]	V _{CC_{ST}} [V]
VIDSOUT	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	100	100	0	10	1.0
VIDSCK							Empty	45	0	50	
VIDALERT #							56	Empty	220	0	

Note: For additional information regarding SVID and power management refer to "[Power Architecture Guide](#)".

Table 14-15. SVID Minimum Spacing Guidelines

Coupling length [inches]	Stripline [mils]	Microstrip [mils]
<0.5	5	5
<2.5	10	10
>2.5	12	15

14.2.14 COMP Signals

Refer to Coffee Lake Processor External Design Specification (EDS) Volume 1 of 2 for termination requirements for all COMP signals.

14.3 ESD Protection for Asynchronous Signals

Asynchronous signals are not subject to signal integrity issues but could be victims of ESD events resulting in catastrophic system failures. Therefore, some of them deserve extra care during board routing: good referencing from top or bottom layer, placement of noise filters, no exposure to the edges of a board.

Refer to [Chapter 49, "Electromagnetic Compatibility"](#) for the detailed info on ESD sensitive nets and their treatments.

§ §



15 Flexible I/O

15.1 Overview

Flexible Input/Output (I/O) is a technology that allows some of the PCH High Speed I/O (HSIO) lanes to be configured for connection to a Gigabit Ethernet (GbE) Controller, a PCIe* Controller, or a Extensible Host Controller Interface (XHCI) USB 3.1 Controller, or a Advanced Host Controller Interface (AHCI) SATA Controller. Flexible I/O enables customers to optimize the allocation of the PCH HSIO interfaces to better meet the I/O needs of their system.

Note: Some Flexible I/O muxing capabilities are not available on all SKUs. Refer to the PCH External Design Specifications (EDS) for specific SKU implementation details.

15.2 Flexible I/O Implementation

15.2.1 Cannon Lake HPCH-H

Figure 15-1. High Speed I/O (HSIO) Lane Multiplexing in PCH-H

Flex I/O Lane	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29		
High Speed I/O (HSIO) Type and Lane	PCIe * #5	PCIe * #10	PCIe * #11	PCIe * #12	SATA 1a	SATA 0a	SATA 0b	GbE	GbE	GbE	PCIe * #9	PCIe * #8	PCIe * #7	PCIe * #6	PCIe * #5	USB3.1 Gen1 #10	USB3.1 Gen1 #9	USB3.1 Gen1 #8	USB3.1 Gen1 #7	USB3.1 Gen1/Gen2 #6	USB3.1 Gen1/Gen2 #5	USB3.1 Gen1/Gen2 #4	USB3.1 Gen1/Gen2 #3	USB3.1 Gen1/Gen2 #2	USB3.1 Gen1/Gen2 #1	SATA 5	SATA 6	SATA 7	SATA 4	SATA 3	SATA 2	SATA 1b
Intel® RST Support					No Support	No Support	Yes	No Support	No Support	Yes																						

The 30 HSIO lanes on PCH-H supports the following configurations:

1. Up to 24 PCIe* Lanes
 - A maximum of 16 PCIe* Ports (or devices) can be enabled
 - When a GbE Port is enabled, the maximum number of PCIe* Ports (or devices) that can be enabled reduces based off the following:
Max PCIe* Ports (or devices) = 16 - GbE (0 or 1)



- PCIe* Lanes 1-4 (PCIe* Controller #1), 5-8 (PCIe* Controller #2), 9-12 (PCIe* Controller #3), 13-16 (PCIe* Controller #4), 17-20 (PCIe* Controller #5), and 21-24 (PCIe* Controller #6) can be individually configured
2. Up to 10 SATA Lanes
 - A maximum of 8 SATA Ports (or devices) can be enabled
 - SATA Lane 0 has the flexibility to be mapped to Flex I/O Lane 16 or 18
 - SATA Lane 1 has the flexibility to be mapped to Flex I/O Lane 17 or 19
 3. Up to 6 USB3.1 Gen1/Gen2 Lanes and 4 USB3.1 Gen1 Lanes
 - A maximum of 10 USB3.1 Ports (or devices) can be enabled
 - USB3.1 Gen1 = 5 GT/s
 - USB3.1 Gen2 = 10 GT/s
 4. Up to 4 GbE Lanes
 - A maximum of 1 GbE Port (or device) can be enabled
 5. Supports up to 3 Remapped (Intel® Rapid Storage Technology) PCIe* storage devices
 - x2 and x4 PCIe* NVMe SSD
 - x2 and x4 Next Generation Intel® Optane™ Memory
 - See the “PCI Express* (PCIe*)” chapter for the PCH PCIe* Controllers, configurations, and lanes that can be used for Intel® Rapid Storage Technology PCIe* storage support
 6. For unused SATA/PCIe* Combo Lanes, Flex I/O Lanes that can be configured as PCIe* or SATA, the lanes must be statically assigned to SATA or PCIe* via the SATA/PCIe Combo Port Soft Straps discussed in the SPI Programming Guide and through the Intel® Flash Image Tool (FIT) tool.



16 PCH PCI Express® Interface Design Guidelines

16.1 PCH PCI Express® Interface Configuration Details

Figure 16-1. Supported PCH PCI Express® Link Configurations

PCH-H Details	PCIe® Controller #1				PCIe® Controller #2				PCIe® Controller #3				PCIe® Controller #4				PCIe® Controller #5				PCIe® Controller #6			
									Cycle Router #1								Cycle Router #3				Cycle Router #2			
Flex I/O Lane #	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
PCIe® Lane #	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24
HM370	1x4								RP 9				RP 13				RP 17				RP 21			
	1x4 LR								RP 9				RP 13				RP 17				RP 21			
	2x2								RP 5				RP 13				RP 17				RP 21			
	1x2+2x1								RP 9				RP 11				RP 13				RP 21			
	2x1+1x2								RP 12				RP 3				RP 13				RP 20			
	4x1								RP 9				RP 10				RP 12				RP 13			
QM370	1x4								RP 5				RP 9				RP 13				RP 17			
	1x4 LR								RP 5				RP 9				RP 13				RP 21			
	2x2								RP 5				RP 7				RP 9				RP 21			
	1x2+2x1								RP 5				RP 7				RP 9				RP 21			
	2x1+1x2								RP 8				RP 5				RP 12				RP 13			
	4x1								RP 5				RP 6				RP 7				RP 8			
CM246	1x4				RP 1				RP 5				RP 9				RP 13				RP 17			
	1x4 LR				RP 1				RP 5				RP 9				RP 13				RP 21			
	2x2				RP 1				RP 3				RP 5				RP 9				RP 21			
	1x2+2x1				RP 1				RP 3				RP 5				RP 7				RP 8			
	2x1+1x2				RP 4				RP 3				RP 1				RP 5				RP 6			
	4x1				RP 1				RP 2				RP 4				RP 5				RP 7			

Notes:

1. RP# refers to a specific PCH PCI Express® Root Port #; for example RP3 = PCH PCI Express® Root Port 3
2. A PCIe® Lane is composed of a single pair of Transmit (TX) and Receive (RX) differential pairs, for a total of four data wires per PCIe® Lane (such as, PCIE[3]_TXP/PCIE[3]_TXN and PCIE[3]_RXP/PCIE[3]_RXN make up PCIe Lane 3). A connection between two PCIe® devices is known as a PCIe® Link, and is built up from a collection of one or more PCIe® Lanes which make up the width of the link (such as bundling 2 PCIe® Lanes together would make a x2 PCIe® Link). A PCIe® Link is addressed by the lowest number PCIe® Lane it connects to and is known as the PCIe® Root Port (such as a x2 PCIe® Link connected to PCIe® Lanes 3 and 4 would be called x2 PCIe® Root Port 3).
3. The PCIe® Lanes can be configured independently from one another but the max number of configured Root Ports (Devices) must not be exceeded
 - PCH-H supports a maximum of 16 PCIe® Root Ports (or devices) can be enabled
 - When a GbE Port is enabled, the maximum number of PCIe® Ports (or devices) that can be enabled reduces based off the following:
 - PCH-H Max PCIe® Ports (or devices) = 16 - GbE (0 or 1)
4. Unidentified lanes within a PCIe® Link Configuration are disabled but their physical lanes are used for the identified Root Port
5. Supports up to Three Remapped (Intel® Rapid Storage Technology) PCIe® Storage Devices
 - Cells highlighted in Green identify controllers, configurations, and lanes that can be used for a x2 or x4 Intel® Rapid Storage Technology Remapped PCIe® NVMe SSD or a x2 or x4 Next Generation Intel® Optane™ Memory Device
6. The SRCCLKREQ#[15:0] signals can be configured to map to any of the PCI Express® Root Ports
7. SRCCLKREQ#[15:0] to CLKOUT_PCIE_P/N[15:0] Mapping Requirements
 - SRCCLKREQ#[7:0] signals can be mapped to any of the CLKOUT_PCIE_P/N[7:0] differential clock pairs
 - SRCCLKREQ#[15:8] signals can be mapped to any of the CLKOUT_PCIE_P/N[15:8] differential clock pairs
8. Reference and understand the PCIe® High Speed I/O Muxing details covered in the "Flexible I/O" Chapter
9. Lane Reversal Supported Motherboard PCIe® Configurations = 1x4 and 2x1+1x2
 - The 2x1+1x2 configuration is enabled by setting the PCIe® Controller soft straps to 1x2+2x1 with Lane Reversal Enabled
 - 1x4 = 1x4 with Lane Reversal Disabled, 1x4 LR = 1x4 with Lane Reversal Enabled



10. For unused SATA/PCIe* Combo Lanes, Flex I/O Lanes that can be configured as PCIe* or SATA, the lanes must be statically assigned to SATA or PCIe* via the SATA/PCIe Combo Port Soft Straps discussed in the SPI Programming Guide and through the Intel® Flash Image Tool (FIT) tool. These unused SATA/PCIe* Combo Lanes must not be assigned as polarity based.
 - Refer to the "Flexible I/O" chapter for SATA/PCIe* Combo Lane identification

16.2 Intel® Rapid Storage Technology (Intel® RST) for PCH PCIe* Storage

Intel® Rapid Storage Technology for PCIe* Storage includes the PCH PCIe* Controller Remapping Hardware, also referred to as Cycle Routers, and the Intel® RST Driver. The Remapping Hardware is a PCH PCIe* Controller architecture feature that works with the Intel® RST Driver to control and remap PCIe* storage devices to the PCH AHCI SATA Controller.

The PCH has multiple PCIe* Controllers where some, not all, of these Controllers have the Remapping Hardware. These specific PCIe* Controllers along with the Intel® RST Driver handle the remapping for x2 or x4 PCIe* storage devices. Special care must be taken to make sure the correct PCH PCIe* Lanes are used that are associated with these specific PCIe* Controllers. [Figure 6-4](#) describes and identifies all of the Intel® RST PCIe* controller, configuration, and lane support details.

Note:

The Intel® RST for PCIe* Storage support details will vary depending on the PCH SKU. Refer to the Platform Controller Hub (PCH) External Design Specification (EDS) Volume 1 for the complete PCH SKU details

16.3 PCH PCI Express* Signal Descriptions

Table 16-1. PCH PCI Express* Signal Groups

Group	Signal Name	Description
Data	PCIE[24:1]_TXN & PCIE[24:1]_TXP	PCI Express* Transmit Differential-Pair
	PCIE[24:1]_RXN & PCIE[24:1]_RXP	PCI Express* Receive Differential-Pair
RCOMP	PCIE_RCOMP_N and PCIE_RCOMP_P	Impedance Compensation Inputs

16.4 PCH PCI Express® Routing Guidelines

16.4.1 PCH PCI Express® Device Down Guidelines

Figure 16-2. PCH PCI Express® Device Down at 2.5, 5, and 8 GT/s Topology

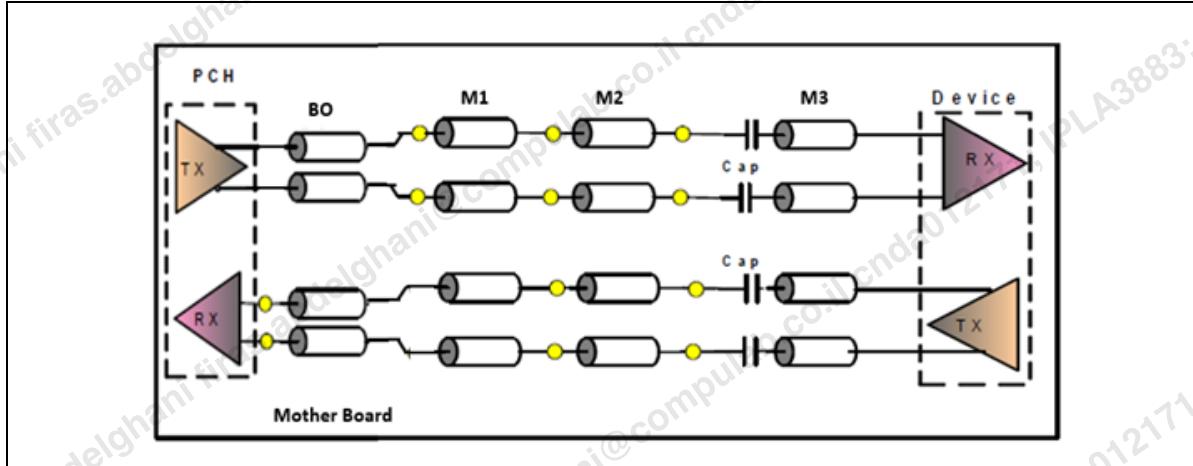


Table 16-2. PCH PCI Express® Device Down Routing Guidelines

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	2.5 GT/s Routing	5GT/s Routing	8 GT/s Routing
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	NA	GND	GND	GND
Break-Out Max Length	BO	MS/SL/DSL	mm(mils)	15.2(598.42)	15.2(598.42)	15.2(598.42)
Post-AC Capacitor Max Length	M3	MS	mm(mils)	8(314.96)	8(314.96)	8(314.96)
Total Motherboard Length Range	BO+M1+M2+M3	BO=MS/SL/DSL M1=MS/SL/DSL M2=MS/SL/DSL M3=MS	mm(mils)	64(2519.68) to 356(14015.75)	64(2519.68) to 279(10984.25)	64(2519.68) to 229(9015.75)
Motherboard Differential Pair Length Matching	BO, M1, M2, M3	MS/SL/DSL	mm(mils)	Within same layer = ± 0.254mm (± 10mils) BO+M1+M2+M3 = ± 0.127mm (± 5mils)		
AC Coupling Capacitor	BO, M3	MS	nF	75 - 265	75 - 265	176 - 265
Max Via Count	BO, M1, M2, M3	NA	vias	6	4	3

Notes:

- For x1 links route the TX and RX signals of each link next to each other on the same layer following interleaved routing
- For x2 and x4 links route the TX and RX signals non-interleaved or semi-interleaved routing in separate groups. Non-interleaved routing is preferred to reduce the effects of cross talk
- The Break-Out Segment (BO) if needed, may start with an initial 4mm (157.48 mils) in length of tighter pair-to-pair spacing of 0.11mm to 0.16mm (4 -6 mils)
- Although min and max capacitor values are shown, 220 nF nominal capacitors are recommended for Gen 3 compliance
- Although min and max capacitor values are shown, 100 nF nominal capacitors are recommended for Gen 2.
- AC coupling capacitors on motherboard are recommended to be placed closer to either the connector or processor side. Avoid placing AC caps at the center of the motherboard
- Micro-Vias within the breakout area are not counted against maximum via total
- Any PCI Express® Transmit and associated Receive Differential Pair not being used or implemented on the platform must be left as no connects

16.4.2 PCH PCI Express* Add-In Card Connector Guidelines

Figure 16-3. PCH PCI Express* Add-In Card Connector Topology

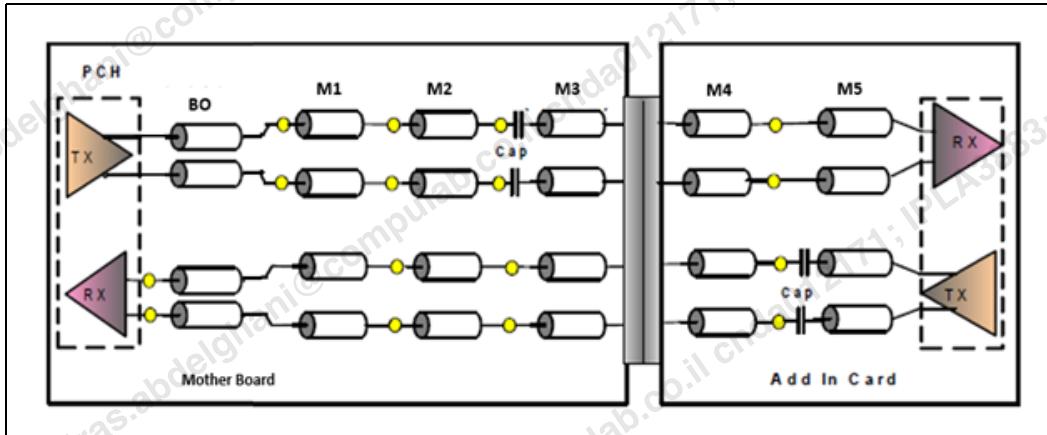


Table 16-3. PCH PCI Express* Add-In Card Connector Routing Guidelines

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	2.5 GT/s Routing	5 GT/s Routing	8 GT/s Routing
Reference Plane	BO, M1, M2, M3, M4, M5	MS/SL/DSL	NA	GND	GND	GND
Break-Out Max Length	BO	MS/SL/DSL	mm(mils)	15.2(598.42)	15.2(598.42)	15.2(598.42)
Post-AC Capacitor Max Length	M3	MS	mm(mils)	8(314.96)	8(314.96)	8(314.96)
Card Break-In Max Length	M5	MS	mm(mils)	8(314.96)	8(314.96)	8(314.96)
Total Motherboard Length Range	BO+M1+M2+M3	BO=MS/SL/DSL M1=MS/SL/DSL M2=MS/SL/DSL M3=MS	mm(mils)	64(2519.68) to 330(12992.13)	64(2519.68) to 229(9015.75)	64(2519.68) to 203(7992.13)
Add-in-Card Max Length	M4+M5	MS	mm(mils)	38(1496.06)	38(1496.06)	38(1496.06)
Motherboard Differential Pair Length Matching	BO, M1, M2, M3	MS/SL/DSL	mm(mils)	Within same layer = $\pm 0.254\text{mm}$ ($\pm 10\text{mils}$) BO+M1+M2+M3 = $\pm 0.127\text{mm}$ ($\pm 5\text{mils}$)		
AC Coupling Capacitor	BO, M3	MS	nF	75 - 265	75 - 265	176 - 265
Motherboard Max Via Count	BO, M1, M2, M3	NA	vias	RX = 4 TX = 4	RX = 4 TX = 4	RX = 2 TX = 3
Add-In Card Max Via Count	M4, M5	NA	vias	1	1	1

Notes:

- For x1 links route the TX and RX signals of each link next to each other on the same layer following interleaved routing
- For x2 and x4 links route the TX and RX signals non-interleaved or semi-interleaved routing in separate groups. Non-interleaved routing is preferred to reduce the effects of cross talk
- The Break-Out Segment (BO) if needed, may start with an initial 4mm (157.48 mils) in length of tighter pair-to-pair spacing of 0.11mm to 0.16mm (4 - 6 mils)
- Although min and max capacitor values are shown, 220 nF nominal capacitors are recommended for Gen 3 compliance
- Although min and max capacitor values are shown, 100 nF nominal capacitors are recommended for Gen 2.
- AC coupling capacitors on motherboard are recommended to be placed closer to the Add-In Card Connector side. Avoid placing AC caps at the center of the motherboard
- Micro-Vias within the breakout area are not counted against maximum via total
- Any PCI Express* Transmit and associated Receive Differential Pair not being used or implemented on the platform must be left as no connects

16.4.3 PCH PCI Express® with Internal Cable Guidelines

Figure 16-4. PCH PCI Express® with Internal Cable Topology

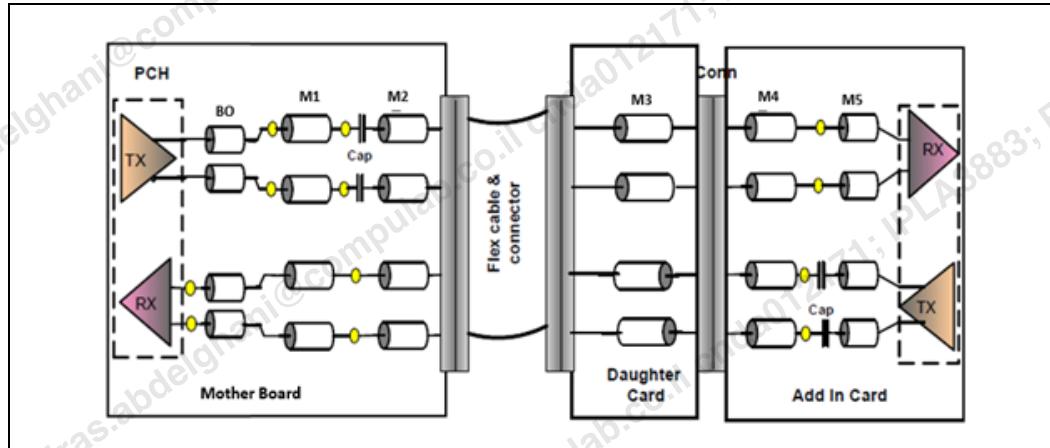


Table 16-4. PCH PCI Express® with Internal Cable Routing Guidelines

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	2.5 GT/s Routing	5 GT/s Routing	8 GT/s Routing
Reference Plane	BO, M1, M2, M3, M4, M5	MS/SL/DSL	NA	GND	GND	GND
Break-Out Max Length	BO	MS/SL/DSL	mm(mils)	15.2(598.42)	15.2(598.42)	15.2(598.42)
Post-AC Capacitor Max Length	M2	MS	mm(mils)	8(314.96)	8(314.96)	8(314.96)
Card Break-In Max Length	M5	MS	mm(mils)	8(314.96)	8(314.96)	8(314.96)
Total Length Range	BO+M1+M2+M3+M4+M5	BO=MS/SL/DSL M1=MS/SL/DSL M2=MS/SL/DSL M3=MS	mm(mils)	See Table Below	See Table Below	See Table Below
Add-in-Card Max Length	M4+M5	MS	mm(mils)	38(1496.06)	38(1496.06)	38(1496.06)
Motherboard Differential Pair Length Matching	BO, M1, M2	MS/SL/DSL	mm(mils)	Within same layer = ± 0.254mm (± 10mils) BO+M1+M2 = ± 0.127mm (± 5mils)		
AC Coupling Capacitor	M2, M5	MS	nF	75 - 265	75 - 265	176 - 265
Motherboard Max Via Count	BO, M1, M2, M3	NA	vias	RX = 2 TX = 2	RX = 1 TX = 2	RX = 1 TX = 2
Add-In Card Max Via Count	M4, M5	NA	vias	1	1	1

Notes:

- For x1 links route the TX and RX signals of each link next to each other on the same layer following interleaved routing
- For x2 and x4 links route the TX and RX signals non-interleaved or semi-interleaved routing in separate groups. Non-interleaved routing is preferred to reduce the effects of cross talk
- The Break-Out Segment (BO) if needed, may start with an initial 4mm (157.48 mils) in length of tighter pair-to-pair spacing of 0.11mm to 0.16mm (4 -6 mils)
- Although min and max capacitor values are shown, 220 nF nominal capacitors are recommended for Gen 3 compliance
- Although min and max capacitor values are shown, 100 nF nominal capacitors are recommended for Gen 2.
- AC coupling capacitors on motherboard are recommended to be placed closer to the Connector side. Avoid placing AC caps at the center of the motherboard
- Micro-Vias within the breakout area are not counted against maximum via total
- Any PCI Express® Transmit and associated Receive Differential Pair not being used or implemented on the platform must be left as no connects

Table 16-5. PCH PCI Express* with Internal Cable Routing Length versus Cable Loss

Up to 2.5 GHz (Gen2)		Up to 4.0 GHz (Gen3)	
Total Length B0+M1+M2+M3+M4+M5	Cable Loss	Total Length B0+M1+M2+M3+M4+M5	Cable Loss
3000 mils (76.2 mm)	3.5 dB	3000 mils (76.2 mm)	3.0 dB
3500 mils (88.9 mm)	3 dB		
4500 mils (114.3 mm)	2.5 dB		
5500 mils (139.7 mm)	2 dB		
6500 mils (165.1 mm)	1.5 dB		
7000 mils (177.8 mm)	1 dB		

16.4.4 PCH PCI Express* M.2 Socket Module Guidelines

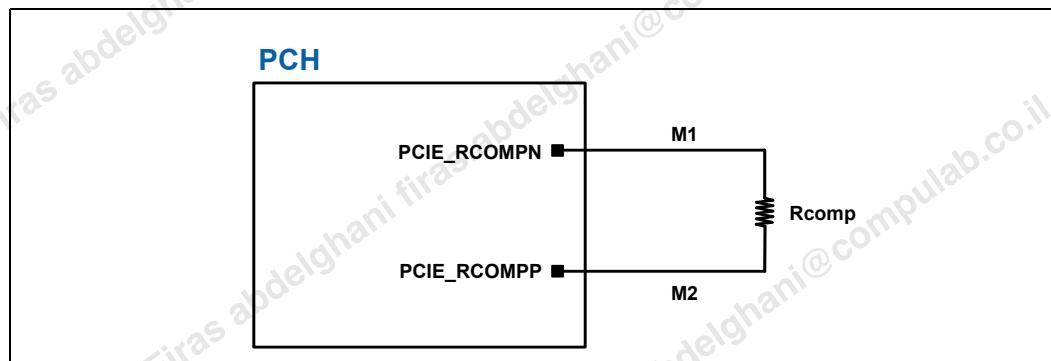
The routing guidelines for a PCIe* interface used with an M.2 Socket Module are covered in the "M.2 - Next Generation Form Factor (NGFF)" chapter.

Note:

Intel® Optane™ Memory Device support requires the following:

- M.2 Socket 2 or a M.2 Socket 3 form factor module connector
- Connect PCH PLTRST# to the M.2 Socket PLTRST# module pin
- Connect a PCH SRCCLKREQ# pin to the M.2 Socket CLKREQ# module pin

16.4.5 PCH PCI Express* Impedance Compensation Guidelines

Figure 16-5. PCH PCIE_RCOMPNN and PCIE_RCOMPP Connections

Table 16-6. PCH PCI Express* Compensation Routing Guidelines (Sheet 1 of 2)

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	2.5 GT/s Routing	5 GT/s Routing	8 GT/s Routing
Reference Plane	M1, M2	MS/SL/DSL	NA	GND	GND	GND
Series Resistor	M1, M2	MS	Ohms	100 +/-1%	100 +/-1%	100 +/-1%
Motherboard Max Via Count	M1, M2	NA	vias	2	2	2
Motherboard Length Matching	M1, M2	MS/SL/DSL	mm(mils)	M1- M2 = ± 0.127mm (± 5mils)		

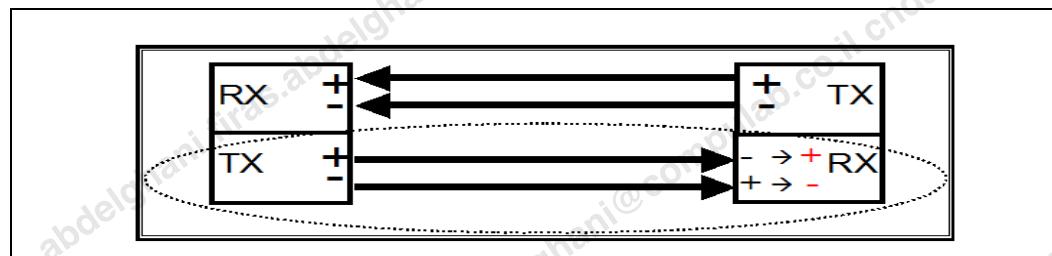
**Table 16-6. PCH PCI Express® Compensation Routing Guidelines (Sheet 2 of 2)**

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	2.5 GT/s Routing	5 GT/s Routing	8 GT/s Routing
Notes:						
1. Recommended placing a VSS shield of at least 4mils (0.1016mm) wide between the RCOMP signals and any adjacent I/O signal 2. Avoid routing close to any clocks 3. Micro-Vias within the breakout area are not counted against maximum via total 4. Must maintain low DC resistance routing (<0.1 ohm)						

16.4.6 PCH PCI Express® Lane Polarity Inversion

The PCI Express® Base Specification requires polarity inversion to be supported independently by all receivers across the Link where each differential pair within each Lane of the PCIe® Link handles its own polarity inversion. Polarity inversion does not imply direction inversion or direction reversal; that is, the Tx differential pair from one device must still connect to the Rx differential pair on the receiving device, per the PCIe® Base Specification.

Note: Polarity Inversion is not the same as "PCI Express® Controller Lane Reversal"

Figure 16-6. PCH Polarity Inversion on a TX to RX Interconnect

16.4.7 PCH PCI Express® Controller Lane Reversal

For each PCH PCIe® Controller we support end-to-end lane reversal across the four lanes mapped to a controller for the following two motherboard PCIe® configurations

Notes:

- Lane Reversal Supported Motherboard PCIe® Configurations = 1x4 and 2x1+1x2
 - The 2x1+1x2 configuration is enabled by setting the PCIe® Controller soft straps to 1x2+2x1 with Lane Reversal Enabled.
- PCH PCI Express® Controller Lane Reversal is not the same as PCI Express® Lane Polarity Inversion

Table 16-7. PCH PCIe* Configuration Lane Reversal Mapping

PCIe* Configuration	PCI Express* Lanes						PCI Express* Down Device or Connector Lanes
	PCIe* Controller #1	PCIe* Controller #2	PCIe* Controller #3	PCIe* Controller #4	PCIe* Controller #5	PCIe* Controller #6	
1x4	1	5	9	13	17	21	3
	2	6	10	14	18	22	2
	3	7	11	15	19	23	1
	4	8	12	16	20	24	0
2x1+1x2	1	5	9	13	17	21	0
	2	6	10	14	18	22	0
	3	7	11	15	19	23	1
	4	8	12	16	20	24	0

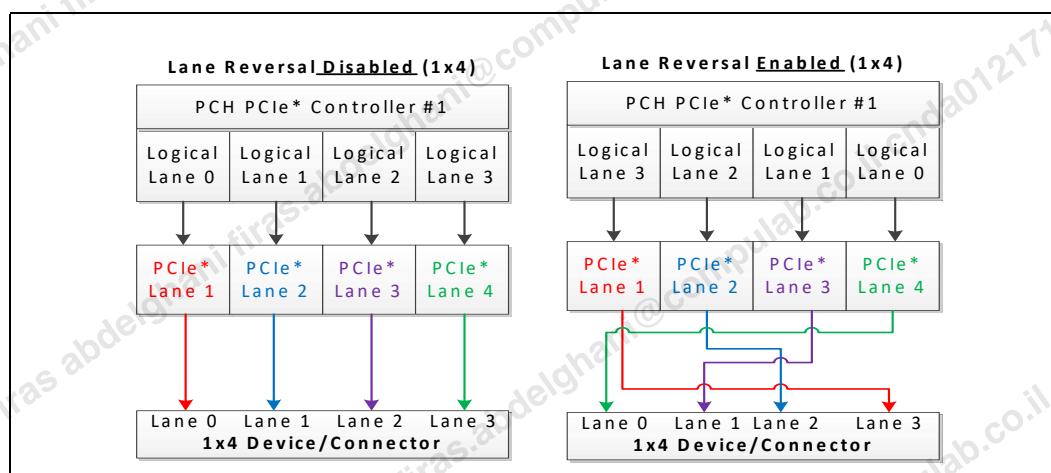
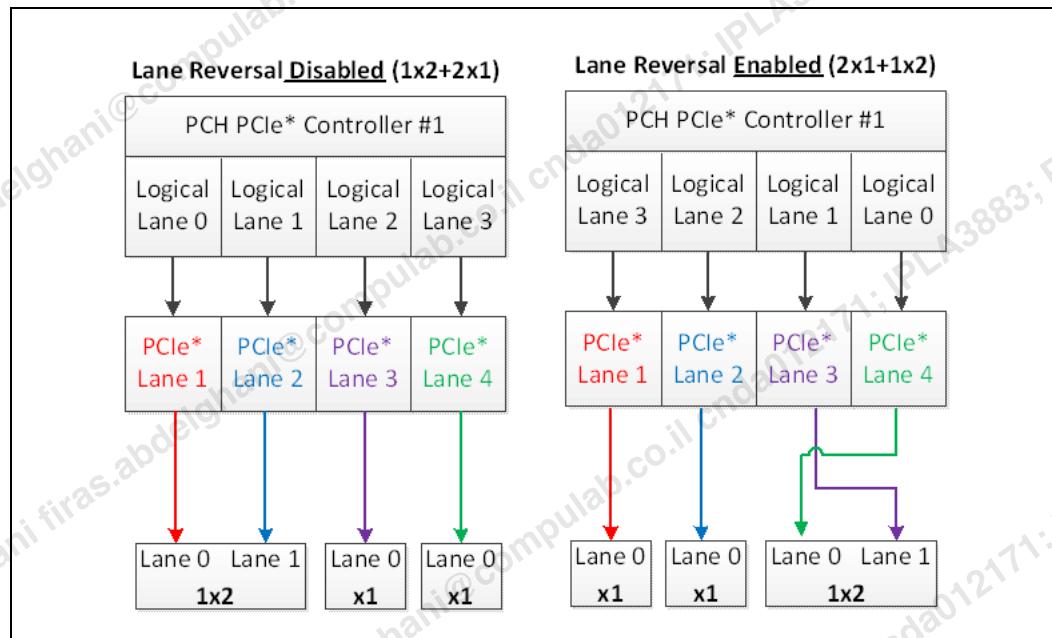
Figure 16-7. 1x4 Configuration PCH PCIe* Lane Reversal Example


Figure 16-8. 2x1+1x2 Configuration PCH PCI Express® Lane Reversal Example





17 SATA Interface Guidelines

17.1 Overview

The following sections provides routing requirements and trace guidelines for SATA Gen 1 (1.5 Gb/s), Gen 2 (3 Gb/s), and SATA Gen 3 (6 Gb/s).

The PCH supports up to six SATA ports that is capable of independent DMA operation. The SATA controllers are completely software transparent with an AHCI interface and only supports AHCI mode using memory space (IDE mode is not supported).

Table 17-1. SATA Reference Documents

Title	Document # / Location
SATA-IO Certified Test Laboratories	www.sata-io.org
High Speed Internal Connector and Cable – Specification	549136
An Electrical Study on the Implementation of 85Ω Nominal Differential Impedance Transmission Lines in High-Speed Serial ATA Interface - Technical White Paper	549023

Table 17-2. SATA Compliance Documents

Title	Document # / Location
Serial ATA Specification, Revision 3.2	www.sata-io.org
SATA Express Transmitter Test Methodology - Technical White Paper	548875

17.2 SATA Signal Description

17.2.1 SATA Signal Groups

Table 17-3. SATA Signal Groups

Group	Signal Name	Description
SATA Receive	SATA0[B:A]_RXP/RXN, SATA1[B:A]_RXP/RXN, SATA[5:2]_RXP/ RXN	Differential Receive Pair
SATA Transmit	SATA0[B:A]_TXP/TXN, SATA1[B:A]_TXP/TXN, SATA[5:2]_TXP/ TXN.	Differential Transmit Pair
Power Control	DEVS LP[5:0].	Host Controlled Power State
GPIO	SATAGP[5:0]	General Purpose
LED	SATA LED#	LED

17.2.2 SATA Signal Considerations

17.2.2.1 SATA General Purpose (SATAGP) Signals

- The PCH provides six SATA general purpose input signals and can be implemented as interlock switch inputs corresponding to a given SATA port.



- When used as an interlock switch status indication, this signal should be driven to 0 to indicate that the switch is closed and to a 1 to indicate that the switch is open.
- If mechanical presence switches will not be used on the platform, the signals can be used as GPIOs.

17.2.2.2 DEVSLP Implementation

DEVSLP is a host-controlled hardware signal which enables a SATA host and device to enter an ultra-low interface power state, including the possibility to completely power down host and device PHYs.

- When **high**, DEVSLP requests the SATA device to enter into the DEVSLP power state.
- When **low**, DEVSLP requests the SATA device to exit from the DEVSLP power state and transition to active state.
- Align DEVSLP pin assignment 1 host pin to 1 device pin as follows:
 - SATA DEVSLP0 to DEVSLP Port0
 - SATA DEVSLP1 to DEVSLP Port1
 - SATA DEVSLP2 to DEVSLP Port2
 - SATA DEVSLP0 to DEVSLP Port3
 - SATA DEVSLP1 to DEVSLP Port4
 - SATA DEVSLP2 to DEVSLP Port5

Note:

1 DEVSLP pin is required to support EACH DEVSLP enabled RAID storage device. (Example: 2 DEVSLP pins are required to support 2 DEVSLP RAID storage devices).

Important!

- DEVSLP is an open-drain pin on the PCH side and is not required external pull-up or pull-down. The PCH will tri-state this pin to signal to the SATA device that it may enter a lower power state (pin will go high due to pull-up that's internal to the SATA device, per DEVSLP specification). PCH will drive pin low to signal an exit from DEVSLP state.
- DEVSLP is supported in direct connect, mSATA/mPCIe, uSSD, M.2.

17.2.2.3 SATALED# Implementation

The processor provides SATALED# to simplify the indication of SATA devices activity. SATALED# is not intended to source high current design implementation. Use current isolation circuitry for implementation beyond driving an LED activity indicator.

- The SATALED# signal is open-collector and requires a weak external pull-up (8.2 k Ω to 10 k Ω) to Vcc3_3.
- When **low**, SATALED# indicates activity on **any** SATA port.

17.3 SATA General Guidelines

17.3.1 General SATA Routing Guidelines

Refer to [Chapter 2, "Stack-Up and PCB Considerations"](#) for more information on common guidelines for HSIO routing.



Use the following general routing and placement guidelines when laying out a new design.

- **DO NOT** route SATA traces under power connectors, other interface connectors, crystals, oscillators, clock synthesizers, magnetic devices or ICs that use and/or duplicate clocks.
- **DO NOT** place stubs, test points, test vias on the route to minimize reflection. Utilize vias and connector pads as test points instead.
- **DO NOT** serpentine to match RX and TX traces; there is **NO** requirement to match RX and TX traces. In addition, **DO NOT** serpentine to meet minimum length guidelines on RX and TX traces.
- Recommend keeping SATA traces 20 mils from any vias on the motherboard whenever possible.

17.3.2 SATA Test Points and Probing

DO NOT place stubs, test points, test vias on the route to minimize reflection. Use vias and connector pads as test points instead.

17.3.3 SATA Additional Guidelines

17.3.3.1 SATA Link Power Management

Intel recommends the following design options to further reduce SATA link power consumption while supporting hot plug on SATA ports. In general, Intel recommends connecting the Mechanical Present detect pin (SATAGP) to topologies supporting SATA slimline connectors, SATA repeaters, and docking connectors in order to detect hot plug events. The usage of the SATAGP pins must correspond to the port that has the mechanical presence switch implemented (such as, the processor SATA port 0 will use SATAGP0 as the mechanical presence pin).

The following figure is an example of how to implement mechanical presence switches on the motherboard. The exact implementation is dependent upon the platform support and implementation.

Zero Power SATA ODD Guidelines

Zero Power SATA ODD support provides the capability for host software to power off an idle slimline connector-based SATA optical device with a platform. This feature uses the capabilities of the Manufacturing Diagnostic/Device Attention (MD/DA) pin and the Device Present pin in the SATA slimline connector as defined in the *Serial ATA Specification Revision 3.2*.

The Manufacturing Diagnostic / Device Attention (MD/DA) pin provides the capability for the device to notify the PCH in the processor that the device requires service when power has been removed from the drive. This allows the host system to power off the device and be notified when the device requires attention. Typically, this would be when the front panel button is pressed on a tray-load device or when media is inserted in a slot load optical device. To allow proper voltage bias to the device controller, the processor is required to pull-up the MD/DA pin to 3.3 volts using a 10 kΩ pull-up resistor. The Device Attention pin shall be connected to a level-triggered GPIO Input Pin. This GPIO must be capable of generating an SCI event. An additional GPIO is required to control the circuitry that determines the power state of the device. The implementation of this circuitry is the responsibility of the system designer.



The Device Present pin is routed to the respective SATAGP[2:0][5:0] pin (SATAnGP to SATA Portn where n = SATA Port#) that is connected to the AHCI mechanical presence switch of the SATA port. This notifies the host software that the device has been inserted or removed. If the optical device is not physically removable in the system, this pin does not need to be connected. The 3.3V MD/DA pin must be routed according to the SATA Specification.

The 3.3 V MD/DA pin must be asserted by the host before the 5V rail. This ensures that no manufacturing information is sent from the device.

Note:

Support of this feature requires BIOS and AHCI driver support. Refer to the BIOS Specification and/or the ZPODD White paper for additional details.

Figure 17-1. Zero Power ODD Timing Diagram

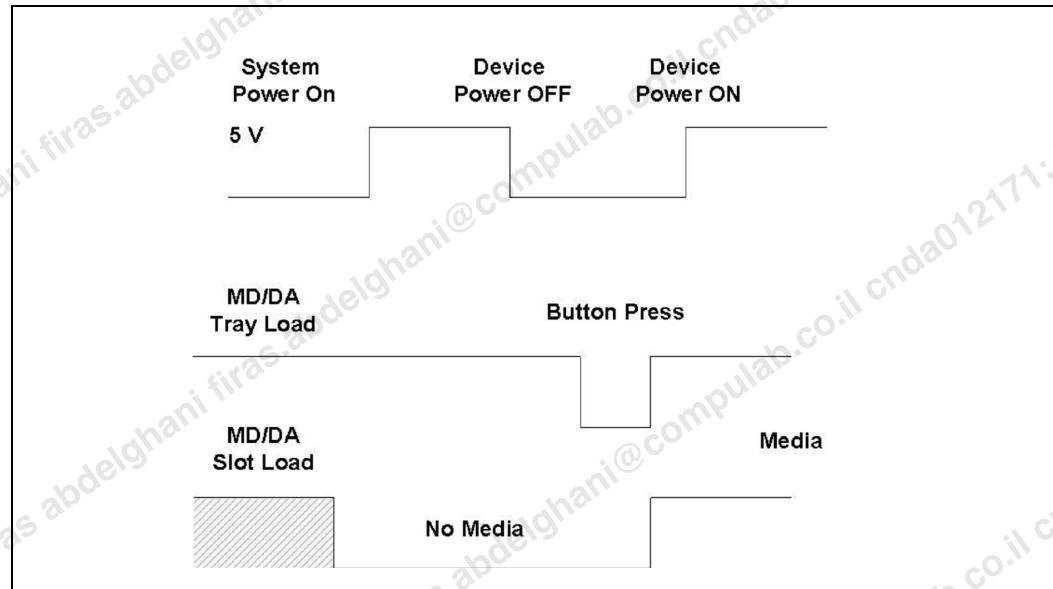


Figure 17-2. Zero Power ODD - Chipset GPIO Implementation Example

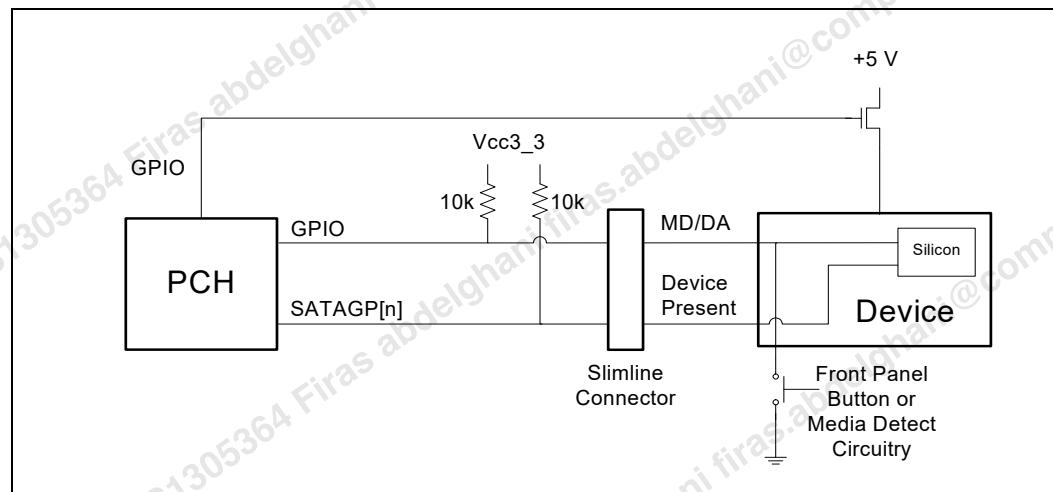
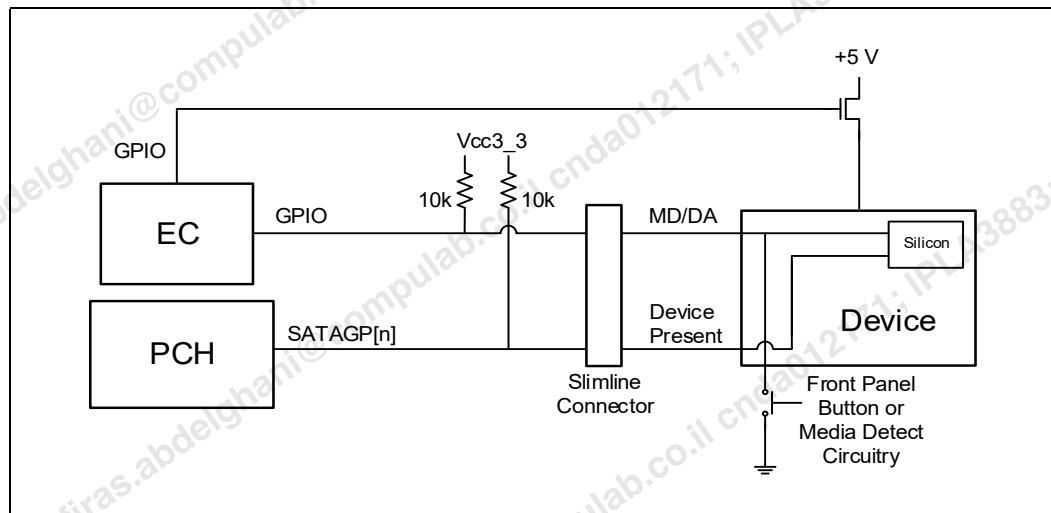


Figure 17-3. Zero Power ODD - Embedded Controller GPIO Implementation Example

17.3.4 SATA Disabling and Termination Guidelines

If a SATA port(s) is not implemented, then SATA[x]_RXP/RXN and SATA[x]_TXP/TXN signals may be left unconnected; where 'x' is the port number left as no connect.

SATA compensation circuit is code share with PCIE_RCOMPP/N differential pair.

Refer to [Chapter 8, "Processor - PCI Express* Design Guidelines"](#)

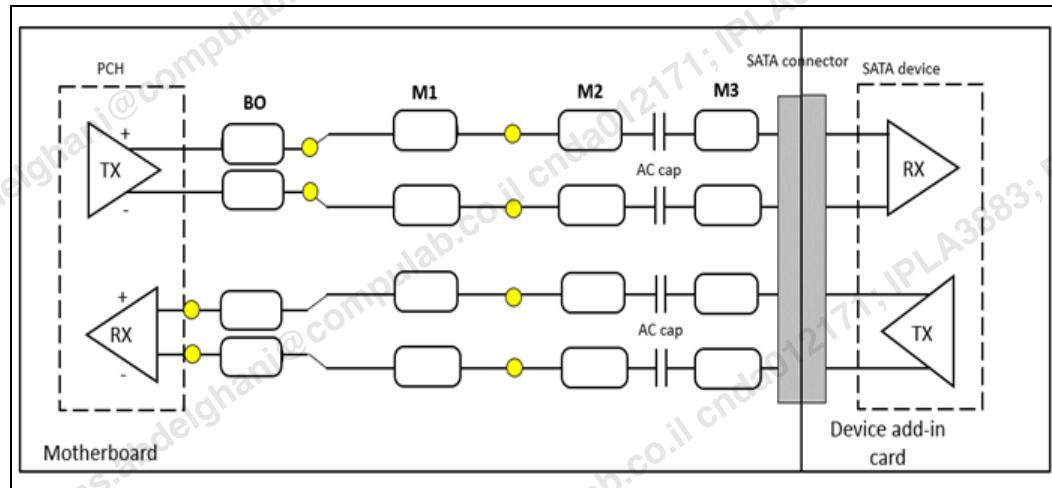
17.4 SATA Topologies and Guidelines

17.4.1 mSATA/Direct Connect

The mSATA/direct connect and M.2 topology supports the routing of a SATA port directly to a connector where the SATA device will be connected directly, without any cable in between.

Note:

For AC Cap implementation if PCIe/SATA muxed port is utilized for these topologies, refer to the AC Capacitor Guidelines in [Table 17-5](#) below for more details.

Figure 17-4. mSATA and Direct Connect Topology**Table 17-4. Routing Guidelines for mSATA and Direct Connect Topology**

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	Gen1/2 Routing	Gen 3 Routing
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	NA	GND	GND
Breakout Max Length	BO	MS/SL/DSL	mm (mils)	15.2 (598.42)	15.2 (598.42)
Post AC capacitor main route length	M3	MS	mm (mils)	10 (393.7)	10 (393.7)
Total Motherboard Length Range	BO+M1+M2 +M3	BO: MS/SL/DSL M1: MS/SL/DSL M2: MS M3: MS	mm (mils)	2 Vias: 50.8 (2000) to 203.2 (8000) (Type 4 PCB) 3 Vias: 50.8 (2000) to 190.5 (7500) (Type 3 PCB)	2 Vias: 50.8 (2000) to 203.2 (8000) 3 Vias: 50.8 (2000) to 178 (7007.87)
Max Via Count	2 or 3 (assuming add-in card having 1 via)				
Notes:					
<ol style="list-style-type: none"> AC capacitor value: 10nF Refer to Chapter 2, "Stack-Up and PCB Considerations" for specific PCB type routing guide. An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 -6 mils) is allowed. The total breakout length is still 15.2mm (598.42 mils) Use a non-interleaved breakout to isolate Tx and Rx. Within the same layer, the mismatch between P and N of a differential pair should be +/- 0.254mm (10 mils), and the total length mismatch should be +/- 0.381mm (15 mils). Continuous GND referencing is preferred. Power plane referencing is allowed. Refer to Chapter 3.5.2 / Power Referencing tab for guidelines and limitations 					

17.4.1.1 AC Capacitor General Guidelines SATA / PCI Express* Multiplexed Ports

The following table summarizes the AC capacitor requirements on the motherboard when using the SATA/PCIe* multiplexed ports. When SATA and PCIe are muxed, always route according to SATA design guidelines. SATA does not support signal polarity reversal and does not support lane reversal.

**Table 17-5. SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values**

Condition	PCI Express* Gen 2 Only	PCI Express* Gen 3 Only	SATA Only	PCI Express* Gen 2 / SATA	PCI Express* Gen 3 / SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ¹	None ²	None ³
Notes:					
1. This option supports all SATA devices. However, the Rx 10 nF capacitor can be removed if DC coupled ODDs / devices are NOT used.					
2. For PCIe* Gen 2/ SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. This option DOES NOT support DC coupled ODDs / Devices.					
3. For PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. This option DOES NOT support DC coupled ODDs / Devices.					
4. Design Constraint: For PCIe* lane that needs to support either PCIe* Gen2 devices or PCIe* Gen3 devices , follow the PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. This option DOES NOT support DC coupled ODDs / Devices.					
5. Use a non-interleaved breakout to isolate Tx and Rx.					

17.4.1.2 Flexible I/O PCIe/SATA Port Selection

The HSIO lanes that have PCIe/SATA port muxing can be statically configured to SATA or PCIe by soft straps.

Note:

Refer to the SPI Programming Guide documentation for details on how to configure the HSIO ports via soft straps.

In addition to static configuration via soft straps, the HSIO lanes that have PCIe/SATA port muxing can be configured dynamically to SATA or PCIe via SATAXPCIE signaling to support implementation like SATA Express, M.2 and mSATA, where the port configuration is selected by the type of the add-in card that is used.

Refer to the SPI Programming Guide documentation for details on how to configure the SATAXPCIE for SATA/PCIe port selection

17.4.2 SATA Direct Connect with Internal Cable Topology

The direct connect with internal cable topology supports the routing of a SATA Gen 1, Gen 2, and Gen 3 ports directly to a connector using an internal connector.

17.4.2.1 Internal Cable Guidelines

The following table provides the guidelines for the internal cable depending on the board trace lengths.

Table 17-6. Internal Connector and Cable Specification

Total Trace Length includes Motherboard and Daughter Card Length (mm or mils)	Internal Cable Assembly Insertion Loss Recommendation up to 3 GHz
50.8 mm	2000 mils
76.2 mm	3000 mils
101.6 mm	4000 mils
127 mm	5000 mils
152.4 mm	6000 mils

There are two implementations, with or without a daughter card, as shown in the two following figures.

17.4.2.2 Without daughter card and with Internal cable

Figure 17-5. SATA Direct Connect with Internal Cable Topology

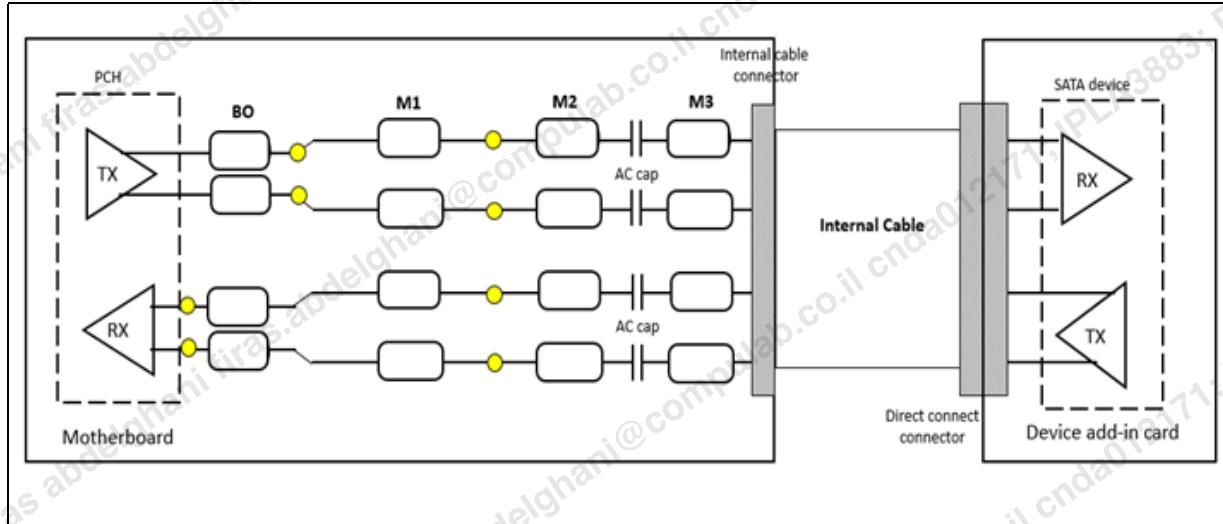


Table 17-7. SATA Direct Connect without daughter card and with Internal Cable Guidelines

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	Routing Guidelines
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	NA	GND
Breakout Max Length	BO	MS/SL/DSL	mm (mils)	15.2 (598.42)
Post AC capacitor main route length	M3	MS	mm (mils)	10 (393.7)
Total Motherboard Length Range	BO+M1+M2+M3	BO: MS/SL/DSL M1: MS/SL/DSL M2: MS M3: MS	mm (mils)	50.8 (2000) to 152 (5984.25)
Max Via Count			2	
Notes:				
1. AC capacitor value: 10nF 2. Refer to Chapter 2, "Stack-Up and PCB Considerations" for specific PCB type routing guide. 3. An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 -6 mils) is allowed. The total breakout length is still 15.2mm (598.42 mils) 4. Use a non-interleaved breakout to isolate Tx and Rx. 5. Within the same layer, the mismatch between P and N of a differential pair should be +/- 0.254mm (10 mils), and the total length mismatch should be +/- 0.381mm (15 mils). 6. Continuous GND referencing is preferred. Power plane referencing is allowed. Refer to Chapter 3.5.2 / Power Referencing tab for guidelines and limitations				

17.4.2.3 With daughter card and with internal cable

Figure 17-6. SATA Direct Connect with Internal Cable

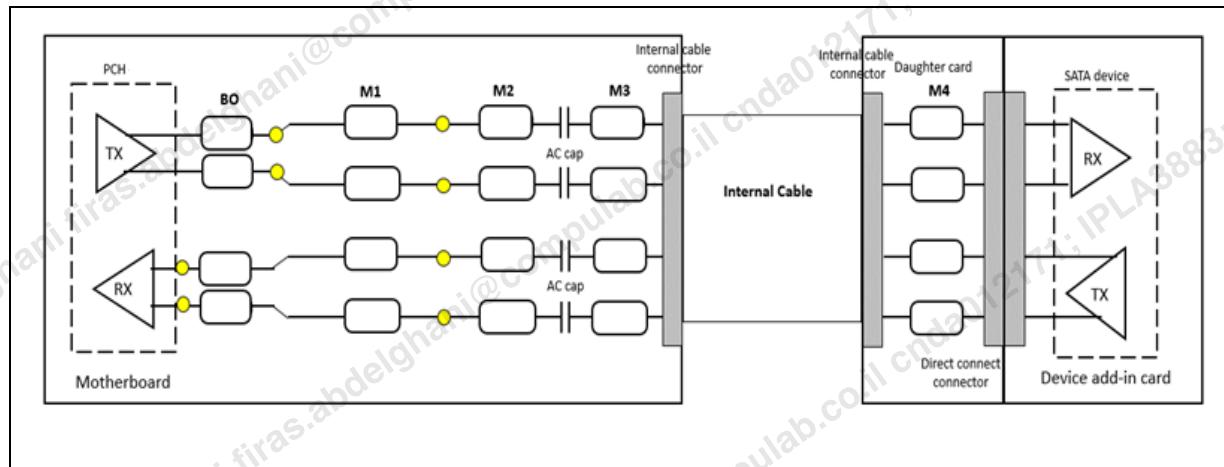


Table 17-8. SATA Direct Connect with Internal Cable Guidelines

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	Routing Guidelines
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	NA	GND
Breakout Max Length	BO	MS/SL/DSL	mm (mils)	15.2 (598.42)
Post AC capacitor main route length	M3	MS	mm (mils)	10 (393.7)
Total Motherboard Length Range	BO+M1+M2+M3	BO: MS/SL/DSL M1: MS/SL/DSL M2: MS M3: MS	mm (mils)	50.8 (2000) to 152 (5984.25)
Max Via Count			2	

Notes:

- AC capacitor value: 10nF
- Refer to Chapter 2, "Stack-Up and PCB Considerations" for specific PCB type routing guide.
- An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 - 6 mils) is allowed. The total breakout length is still 15.2mm (598.42 mils)
- Use a non-interleaved breakout to isolate Tx and Rx.
- Within the same layer, the mismatch between P and N of a differential pair should be +/- 0.254mm (10 mils), and the total length mismatch should be +/- 0.381mm (15 mils).
- Continuous GND referencing is preferred. Power plane referencing is allowed. Refer to Chapter 3.5.2 / Power Referencing tab for guidelines and limitations

17.4.3 Internal SATA (Cable Connect) Topology

Figure 17-7. Internal SATA Topology

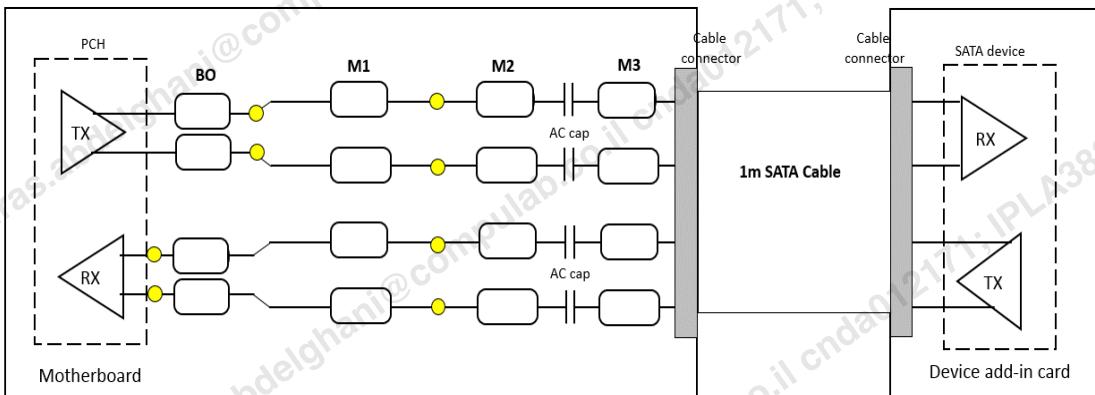


Table 17-9. Routing Guidelines for Internal SATA Topology

Parameter	Segment	Stack-up (MS/SL/DSL)	Units	Routing Guidelines
Reference Plane	BO, M1, M2, M3	MS/SL/DSL	NA	GND
Breakout Max Length	BO	MS/SL/DSL	mm (mils)	15.2 (598.42)
Post AC capacitor main route length	M3	MS	mm (mils)	12.7 (500)
Total Motherboard Length	BO+M1+M2+M3	BO: MS/SL/DSL M1: MS/SL/DSL M2: MS/SL/DSL M3: MS	mm (mils)	50.8 (2000) to 152 (5984.25)
Max Via Count			2	
Notes:				
1. AC capacitor value: 10nF 2. Refer to Chapter 2, "Stack-Up and PCB Considerations" for specific PCB type routing guide. 3. An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 -6 mils) is allowed. The total breakout length is still 15.2mm (598.42 mils) 4. Use a non-interleaved breakout to isolate Tx and Rx. 5. Within the same layer, the mismatch between P and N of a differential pair should be +/- 0.254mm (10 mils), and the total length mismatch should be +/- 0.381mm (15 mils). 6. Continuous GND referencing is preferred. Power plane referencing is allowed. Refer to Chapter 3.5.2 / Power Referencing tab for guidelines and limitations				

17.5 Compliance Requirements

Ensure that the SATA system design is validated and tested for compliance to the SATA specifications. This can be done by executing the Signal Quality Test or by having the system tested by a SATA-IO Certified Test Laboratory. Refer to www.sata-io.org for a list of approved facilities.

§ §



18

Universal Serial Bus USB 3.1 Design Guidelines

Platform Controller Hub (PCH) has an xHCI controller and device controller implemented in it.

Table 18-2. USB 3.1 Reference Documents

Title	Document Number / Location
USB 3.1 Repeater Integration Technical White Paper Rev 0.9	571574
Cannon Lake PCH-H I/O Buffer Information Specification IBIS Models	572079

Table 18-3. USB 3.1 Compliance Documents

Title	Document Number / Location
USB 3.1 Specification	www.usb.org
USB 3.1 Front Panel Cable and Connector Implementation	http://www.usb.org/developers/docs/whitepapers/USB3p1_Front_Panel_CabCon_Implment_Doc_Rev1p0.pdf
USB 3.1 Internal Cable and Connector Implementation	571591

18.1 USB 3.1 Signal Descriptions

18.1.1 Signal Groups

The following table provides a list of the USB 3 interface signals and signal type.

Table 18-4. USB 3.1 Gen2 Interface Signals

Group	Signal Name
USB 3 Differential Transmit Data Pairs	USB31_TXP USB31_TXN
USB 3 Differential Receive Data Pairs:	USB31_RXP USB31_RXN
OverCurrent	USB2_OC#

18.1.2 Overcurrent Protection

The overcurrent signals require a pull-up to the 3.3V Suspend Rail with 8.2–10 KΩ resistor. Additional overcurrent guidance can be found in **Section 19.5, “Overcurrent Protection”**.



18.1.3 USB 3.1 Topology Guidelines

The guidelines provided in this chapter apply to both Type A and HDI boards.

18.1.3.1 USB 3.1 Back Panel Topology

This Topology is defined to be USB 3.1 signals routed directly to a standard and micro-sized Type-A and Type-B connector. Non-interleaved breakout (B0) is required to mitigate concerns on near-end crosstalk. The main route supports interleaved routing and non-interleaved routing for maximum flexibility. However, breakout must be routed using a non-interleaved scheme. Microstrip main route is also recommended albeit with shorter length than Stripline or Dual-Stripline. Routing recommendation is stated in the following table. For additional information refer [Chapter 2, "Stack-Up and PCB Considerations"](#).

These guidelines were developed assuming that the USB 3.1 Device has capacitors on its Tx SS lines. A single $0\ \Omega$ resistor per signal trace should be available to be used to bypass the CMC content if it is proven that there is no EMI risk on USB3.1 Tx/Rx signals. However, the $0\ \Omega$ resistor must be placed near the connector at the same recommended location as the CMC.

Figure 18-1. USB 3.1 Gen1/2 Back Panel Topology

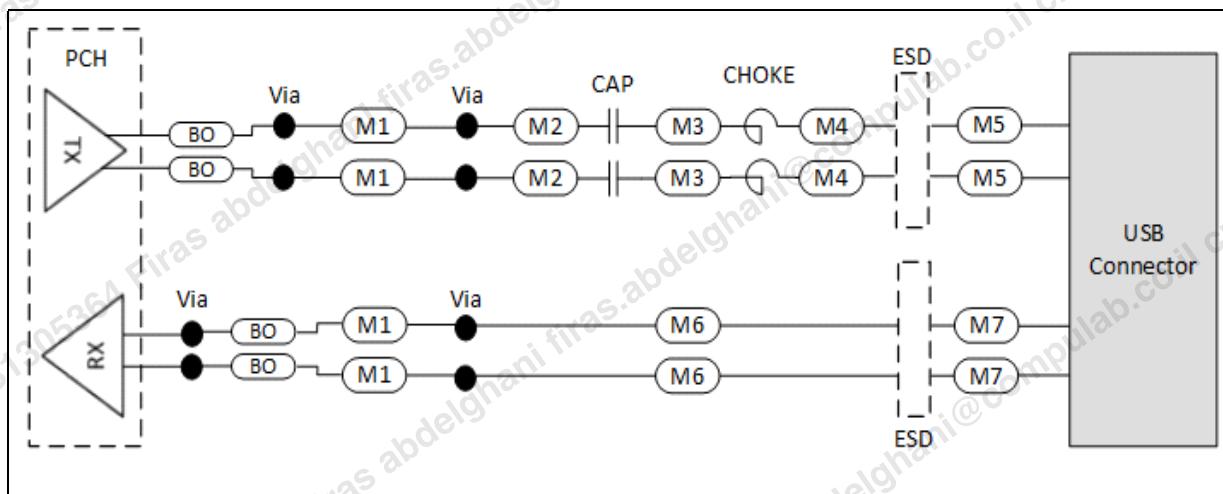


Table 18-5. USB 3.1 Gen1/2 Back Panel Routing Guidelines (Sheet 1 of 2)

	Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)	Maximum Length, Segment (mils)	Max Length, Total (mils)
USB3.1 Gen1	BO	MS/SL/DSL	VSS	1	15.2	228.6	600	9000
	M1	SL/DSL	VSS	1	188.0		7400	
	M2+M3+M4 or M6	MS	VSS	0	10.2		400	
	M5 or M7	MS	VSS	0	15.2		600	

**Table 18-5. USB 3.1 Gen1/2 Back Panel Routing Guidelines (Sheet 2 of 2)**

	Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)	Maximum Length, Segment (mils)	Max Length, Total (mils)		
Notes:										
1. Max total length is 228.6 mm (9000 mils) for SL/DSL and 177.8 mm (7000 mils) for MS										
2. Max M1 length is 188.0 mm (7400) for SL/DSL and 137.2 mm (5400 mils) for MS.										
3. In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.										
USB3.1 Gen2	BO	MS/SL/DSL	VSS	1	10.2	127.0	400	5000		
	M1	MS/SL/DSL	VSS	1	96.5		3800			
	M2+M3+M4 or M6	MS	VSS	0	10.2		400			
	M5 or M7	MS	VSS	0	10.2		400			
Note:										
1. Minimum PCB length is 50.8 mm (2000 mils).										
2. In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.										

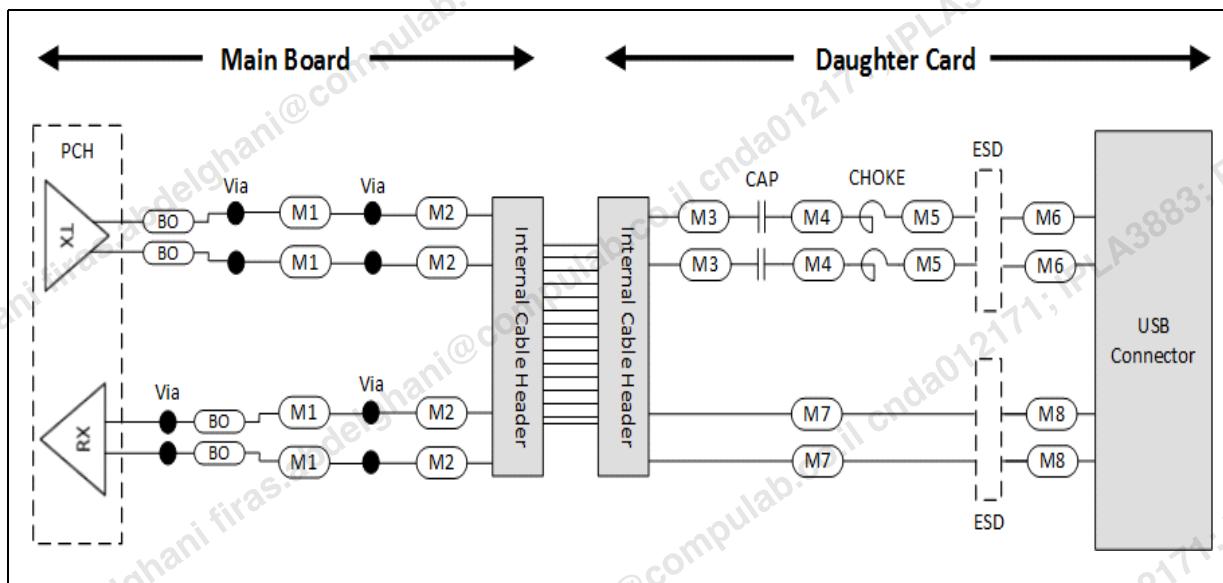
18.1.3.2 USB 3.1 Front Panel Topology

This topology supports a low profile internal connector, internal cable solution. Non-interleaved breakout is required to mitigate concerns on near-end crosstalk. However the main route supports interleaved routing and non-interleaved routing for maximum flexibility.

For signal integrity considerations it is recommended that the USB 3.1 signals are routed to the A-connector via bottom-entry.

Note: It is recommended that the internal connectors and cables adhere to the *High Speed Internal Connector and Cable Specification*.

A single 0Ω resistor per signal trace should be available to be used to bypass the CMC content if it is proven that there is no EMI risk on USB3.1 Tx/Rx signals. However, this component must be placed near the connector at the same recommended location as the CMC.

Figure 18-2. USB 3.1 Gen1/2 Internal Cable Topology

**Table 18-6. USB 3.1 Gen1/2 Internal Cable Topology Routing Guidelines**

	Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)	Maximum Length, Segment (mils)	Max Length, Total (mils)	
USB3.1 Gen1	BO	MS/SL/DSL	VSS	1	15.2	127.0	600	5000	
	M1	SL/DSL	VSS	1	106.7		4200		
	M2	MS	VSS	0	5.1		200		
	M3+M4+M5+M6 or M7+M8	MS	VSS	0	50.8		2000	2000	
Notes:									
1. Max total length on main board (BO+M1+M2) is 127.0 mm (5000 mils) for SL/DSL and 101.6 mm (4000 mils) for MS									
2. Max M1 length is 106.7 mm (4200 mils) for SL/DSL and 81.3 mm (3200 mils) for MS.									
3. In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.									
USB3.1 Gen2	BO	MS/SL/DSL	VSS	1	10.2	63.5	400	2500	
	M1	MS/SL/DSL	VSS	1	48.3		1900		
	M2	MS	VSS	0	5.1		200		
	M3+M4+M5+M6 or M7+M8	MS	VSS	0	12.5		500	500	
Note:									
1. Minimum main board length is 25.4 mm (1000 mils)									
2. In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.									

Table 18-7. USB3.1 Gen1 Internal Cable Differential Insertion Loss Requirements

Motherboard Total Trace Length [SL/DSL;MS] (Inch)	Daughter Card Trace Length (Inch)	Internal Cable Assembly Insertion Loss Recommendation up to 2.5GHz	Internal Cable Assembly Insertion Loss Recommendation up to 5GHz	Internal Cable Assembly Insertion Loss Recommendation up to 7.5GHz
5;4	2	2.0dB	3.5dB	4.8dB
4.5;3.5	2	2.5dB	4dB	6dB
4;3	2	3.0dB	5dB	7dB
3;2	2	3.5dB	6dB	8.5dB
2;1	2	4.0dB	7dB	9.5dB

18.1.3.3 USB 3.1 Re-driver Guidelines

This section provides the necessary guidelines for customers who intend to use re-driver in one of the aforementioned USB 3.1 topologies. Terms such as "re-timer", "repeater", and "re-driver" can be used to describe similar devices: active components used to amplify a signal passing through them. The definitions below are not exhaustive and are only applied in this document in the context of serial links.

Re-driver: An active component, which may have receiver equalization, transmitter de-emphasis, analog signal amplification, etc., to better "shape" the signals passing through it. Re-drivers do not perform retiming (i.e., the device does not implement any interface protocol and no re-sampling is performed). Because it changes the analog



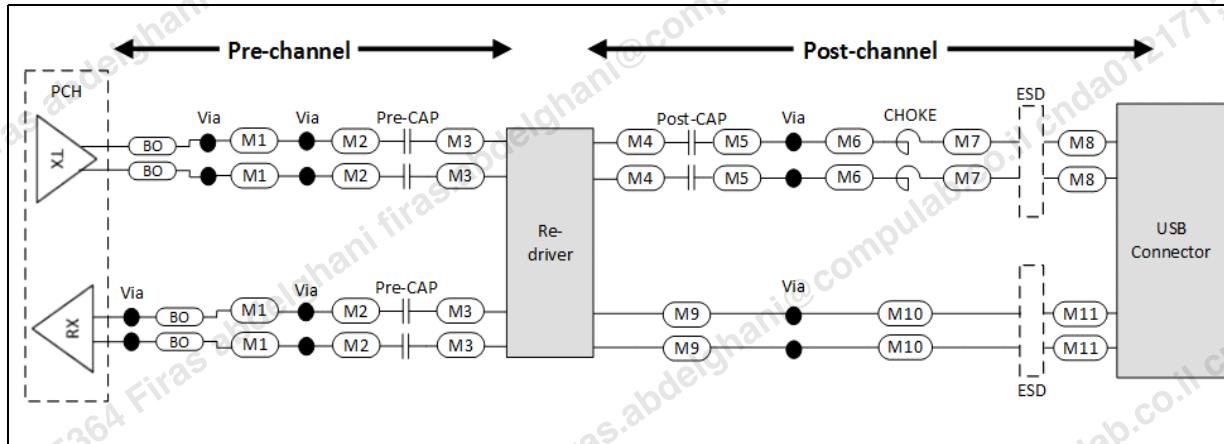
behavior of the incoming signals, the propagation of jitter, noise and other analog effects from one connected channel to the other must be considered. Note that a re-driver's performance is implementation specific in terms of loss compensation.

Re-timer: An active component compliant to the updated Appendix E of the USB 3.1 specification that performs re-sampling of the incoming signal and re-transmitting the recovered signal per specification. A re-timer is protocol aware and compliant to link power management. Note that the delay issue with a re-timer in Gen 1 operation is solved if the implementation follows the updated Appendix E of USB 3.1 Specification document.

For additional details and recommendations regarding the implementation of re-driver in USB3.1 Gen2 channel, refer to the following documents.

Title	Document Number
Intel Channel Checker (ICC) for Client Re-driver CQC Analysis	556174

Figure 18-3. USB 3.1 Gen1/2 Re-driver Topology



**Table 18-8. USB 3.1 Gen1/2 Re-Driver Topology Routing Guidelines**

	Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)
USB3.1 Gen1	BO	MS/SL/DSL	VSS	1	12.7	266.7
	M1	MS/SL/DSL	VSS	1	241.3	
	M2+M3	MS	VSS	0	12.7	
	M4+M5 or M9	MS	VSS	1	7.6	25.4
	M6+M7 or M10	MS	VSS	0	7.6	
	M8 or M11	MS	VSS	0	10.2	
Notes:						
1. Minimum length: Pre-channel is 152.4 mm (6000 mils) & post-channel is 12.7 mm (500 mils)						
2. In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.						
USB3.1 Gen2	BO	MS/SL/DSL	VSS	1	Note1*	Note1*
	M1	MS/SL/DSL	VSS	1	Note1*	
	M2+M3	MS	VSS	0	Note1*	
	M4+M5 or M9	MS	VSS	1	7.6	25.4
	M6+M7 or M10	MS	VSS	0	7.6	
	M8 or M11	MS	VSS	0	10.2	
Note:						
1. Minimum length: Pre-channel is 152.4 mm (6000 mils) & post-channel is 12.7 mm (500 mils)						
2. In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.						

Notes:**Important Guidelines on Repeater/Active MUX topologies**

1. *Max pre-channel length at USB3.1 Gen 2 speeds (10Gb/s) depends on what the specific re-driver based active mux/redriver selected can compensate for when used in conjunction with Intel PCH. Work with repeater vendor to ensure that the component being utilized will provide adequate signal integrity at the PCH.
 - a. OEMs are recommended to use the CRB/RVP topologies as reference for pre-channel lengths which are achievable and validated by Intel.
2. In addition, it is recommended to refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with RDC#571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeater in customer system designs.
3. It is recommended that OEMs use active mux/retimer/redriver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines:
 - a. During power on and receive detect phase, recommended transmitter common mode voltage (V_{cm}) and impedance values:
 - If ($V_{cm} \leq 1.2V$), Repeater Impedance $\geq 1K$ ohm **ELSE**
 - ($V_{cm}+Rx.detect$ pulse amplitude $\leq 2.2V$) **AND** (Repeater Impedance $\geq 4.5K$ ohm).



18.1.3.4 USB 3.1 Re-timer Guidelines

Figure 18-4. USB 3.1 Gen2 Re-timer Topology

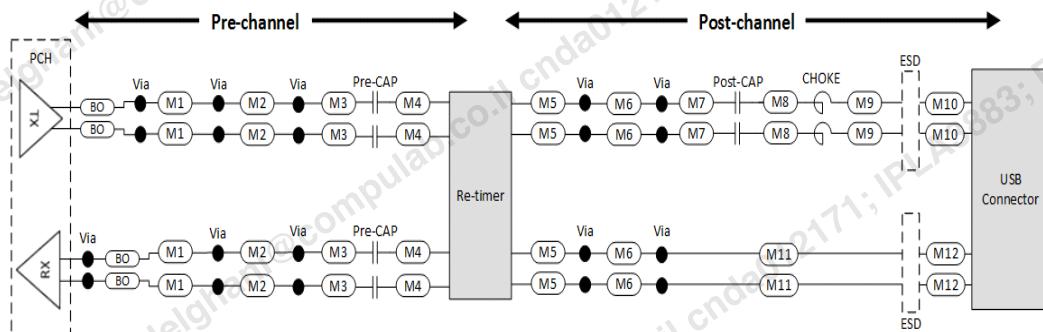


Table 18-9. USB 3.1 Gen2 Re-timer Topology Routing Guidelines

Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)
BO	MS/SL/DSL	VSS	1	10.2	381
M1+M2	MS/SL/DSL	VSS	2	358.1	
M3+M4	MS	VSS	0	12.7	
M5+M6	MS/SL/DSL	VSS	2	101.6	127
M7+M8+M9 or M11	MS	VSS	0	15.2	
M10 or M12	MS	VSS	0	10.2	

Note:

1. Minimum length: Pre-channel & post-channel is 12.7 mm (500 mils)
2. In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.

Notes:

Important Guidelines on Repeater/Active MUX topologies

1. Refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with RDC#571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeater in customer system designs.
2. It is recommended that OEMs use active mux/repeater/redriver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines:
 - a. During power on and receive detect phase, recommended transmitter common mode voltage (V_{cm}) and impedance values:
 - If ($V_{cm} \leq 1.2V$), Repeater Impedance $\geq 1K$ ohm **ELSE**
 - ($V_{cm} + Rx.detect pulse amplitude \leq 2.2V$) **AND** (Repeater Impedance $\geq 4.5K$ ohm).

18.1.4 USB 3.1 Specific Topology Guidelines

Note:

In order to assure adequate EMI and ESD protection, a ESD protection diode should be implemented on each USB data line.

18.1.4.1 USB 3.1 Detachable Docking Topology

Figure 18-5. USB 3.1 Gen1 Detachable Docking Topology

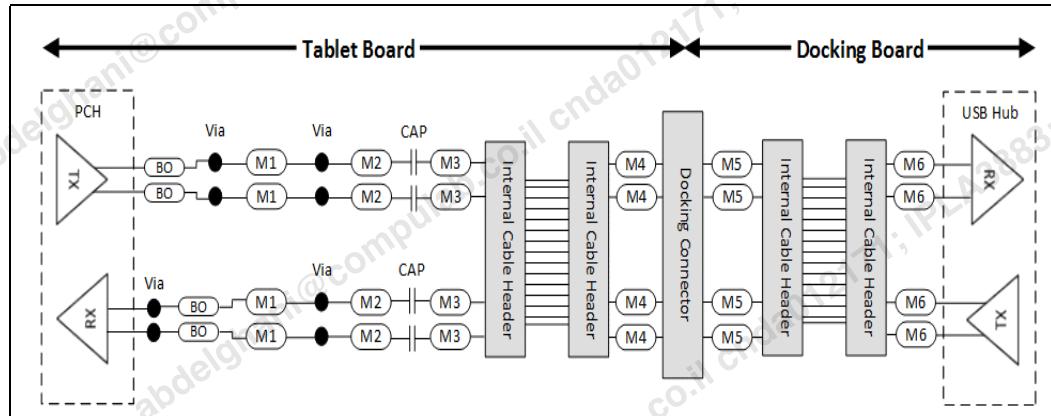


Table 18-10. USB 3.1 Gen1 Detachable Docking Topology Routing Guidelines

Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)
BO	MS/SL/DSL	VSS	1	2.5	165.1
M1	SL/DSL	VSS	1	45.7	
M2+M3	MS	VSS	0	5.1	
M4	SL/DSL	VSS	0	11.7	
M5	SL/DSL	VSS	0	23.9	
M6	SL/DSL	VSS	0	76.2	

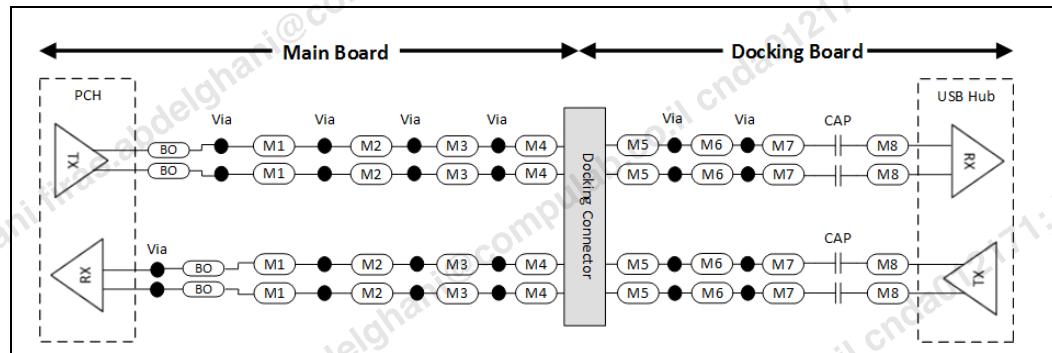
Notes:

Segment	Minimum Length
M1	7.6 mm (300 mils)
M5	11.7 mm (460 mils)
M6	24.9 mm (980 mils)
Total Length	63.5 mm (2500 mil)

**Table 18-11. Trade off of Internal Cable Loss on Margin**

Main Board Total Length (Inches)	Internal Cable Assembly Insertion Loss on Motherboard	Internal Cable Assembly Insertion Loss on Docking
2	4.0dB;4.5dB	4.5dB;4.0dB
1.5	4.5dB;5.0dB	5.0dB;4.5dB
1	5.0dB;5.5dB	5.5dB;5.0dB

18.1.4.2 USB 3.1 Traditional Docking Topology

Figure 18-6. USB 3.1 Gen1 Traditional Docking Topology**Table 18-12. USB 3.1 Gen1 Traditional Docking Topology Routing Guidelines**

Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)
BO	MS/SL/DSL	VSS	1	15.2	355.6
M1+M2+M3+M4	SL/DSL	VSS	3	238.8	
M5+M6	MS/SL/DSL	VSS	2	88.9	
M7+M8	MS	VSS	0	12.7	

Notes:

Microstrip routing is supported for segments M1+M2+M3+M4 at reduced max length compared to SL/DSL	Max Length
M1+M2+M3+M4	188.0 mm (7400 mils)
Total Length	304.8 mm (12000 mils)

18.1.4.3 USB 3.1 M.2 Topology

Figure 18-7. USB 3.1 Gen1 M.2 Topology

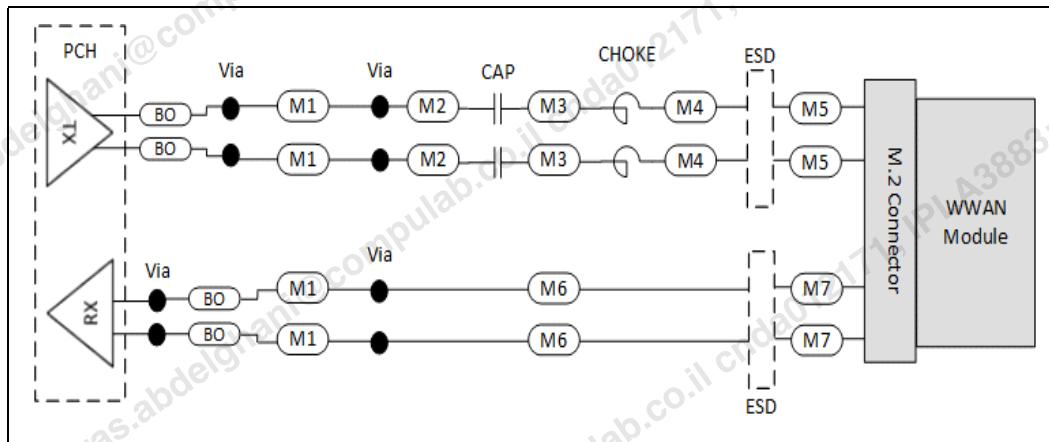


Table 18-13. USB3.1 Gen1 M.2 Topology

Segment	Tline Type	Reference	Via Count	Max Length, Segment (mm)	Max Length, Total (mm)
BO	MS/SL/DSL	VSS	1	15.2	228.6
M1	SL/DSL	VSS	1	188	
M2+M3+M4 or M6	MS	VSS	0	10.2	
M5 or M7	MS	VSS	0	15.2	

Notes:

Microstrip routing is supported for segment M1 at reduced max length compared to SL/DSL	Max Length
M1	137.2 mm (5400 mils)
Total Length	177.8 mm (7000 mils)

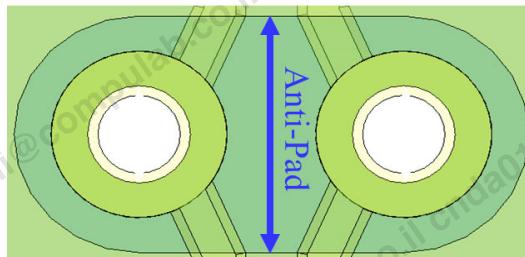
18.1.5 USB 3.1 General Guidelines

- Trace length matching requirement - keep both "within layer" mismatches and "total length" mismatches within 0.127mm, especially for Gen2 signaling. For Gen1, "within layer" max mismatch is 0.254mm and "total length" max mismatch is 0.125mm.
- Breakout scheme: TX and RX breakout at different layers (non-interleaved scheme), for better crosstalk shielding performance
- Breakout length and spacing: An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 -6 mils) is allowed. But the total breakout length should still be within the length defined for each topology.
- Trace Geometry: For Gen2, it is recommended to use 80-ohm trace geometry (with larger trace width), primarily to address routing insertion loss at 10Gbps. For Gen1, it is recommended to use 85-ohm trace geometry (narrower trace width), for PCB



real estate saving. It is worth noting that Gen2 with 80-ohm trace geometry is fully functional and backward compatible with Gen1 5Gbps signaling.

- Reference plane: Continuous Ground
- Via stub: For USB3.1 gen 2, via stub length < 15mils
- Via anti-pad: Oval anti-pad size of 40mils is required for better impedance matching.



- AC capacitor value: 100nF nominal (75-265nF range)
- CMC: CMC is not needed for Rx lanes
- ESD: ESD may/may not be required depending on the 3rd party's device. On the removal of discrete ESD, there are two requirements have to be met:
 - a) Mux/Re-driver can handle the ESD at least 8kV
 - b) Mux/Re-driver to be placed near to USB-C connector (< 1") Refer to 3rd party component specification.
- Distance between coils should be greater than 12 mils (recommended is 15 mils).

18.1.6 USB 3.1 Optimization Guidelines

18.1.7 USB Connector/Receptacle Recommendations

- Proper connector choice is critical to ensure adequate USB signal quality.
- Empirical data has shown that quad-stack USB and DisplayPort*/USB stack connectors may cause Signal quality degradation.
- Proper selection of a motherboard mating connector with USB 3.1 Gen2 support is important to ensure signal quality is not adversely affected due to a poor connector design.
- Refer to usb.org for a list of tested connectors and receptacles.

18.1.7.1 A-Connector Recommendations

- Signals should be launched into the connector from the bottom of the board to minimize the through-hole stub effect. The connector footprint shall have the following through-hole dimensions: 28 mil finished hole, 43 mil pad, and 40 mil anti-pad

18.1.7.2 USB 3.1 Mobile Internal Connector

- It is possible to define the Mobile internal connector pin list based on individual needs. However, an example connector pin list for 2-port USB3 internal cable connection is shown in the following table.

**Table 18-14. Example of Mobile Internal Connector Pin Assignment and Description for Two-Port USB 3.1 Gen2***

Pin Number	Signal	Description
1	RSVD	Reserved pin
2	Vbus	5 V bus power
3	Vbus	5 V bus power
4	Vbus	5 V bus power
5	USB2P_1	USB2 Port 1 D+
6	USB2N_1	USB2 Port 1 D-
7	PWR_GND	Power GND return
8	USB2P_2	USB2 Port 2 D+
9	USB2N_2	USB2 Port 2 D-
10	PWR_GND	Power GND return
11	USB3_1_TXP	USB3 Port 2 SuperSpeed Tx+
12	USB3_1_TXN	USB3 Port 2 Super Speed Tx-
13	SIG_GND	Signal GND return
14	USB3_1_RXP	USB3 Port 2 SuperSpeed Rx+
15	USB3_1_RXN	USB3 Port 2 Super Speed Rx-
16	SIG_GND	Signal GND return
17	USB3_2_TXP	USB3 Port 2 SuperSpeed Tx+
18	USB3_2_TXN	USB3 Port 2 Super Speed Tx-
19	SIG_GND	Signal GND return
20	USB3_2_RXP	USB3 Port 2 SuperSpeed Rx+
21	USB3_2_RXN	USB3 Port 2 SuperSpeed Rx-
22	SIG_GND	Signal GND return

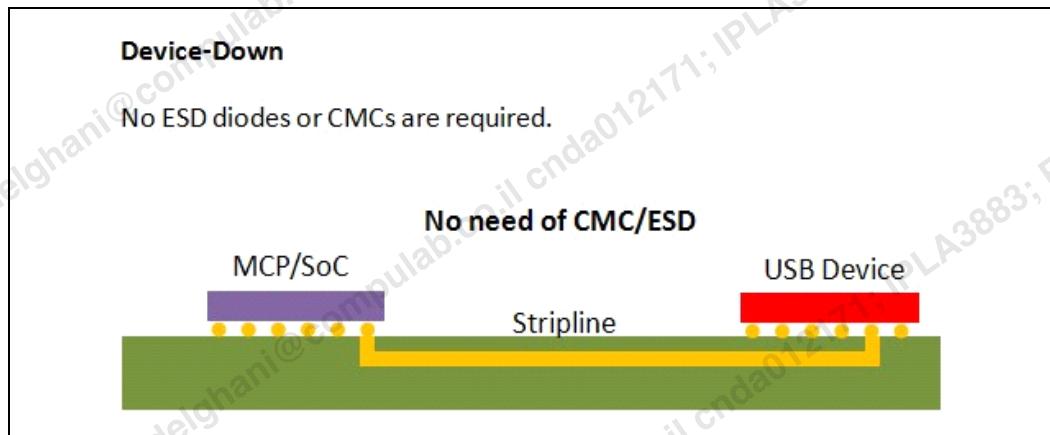
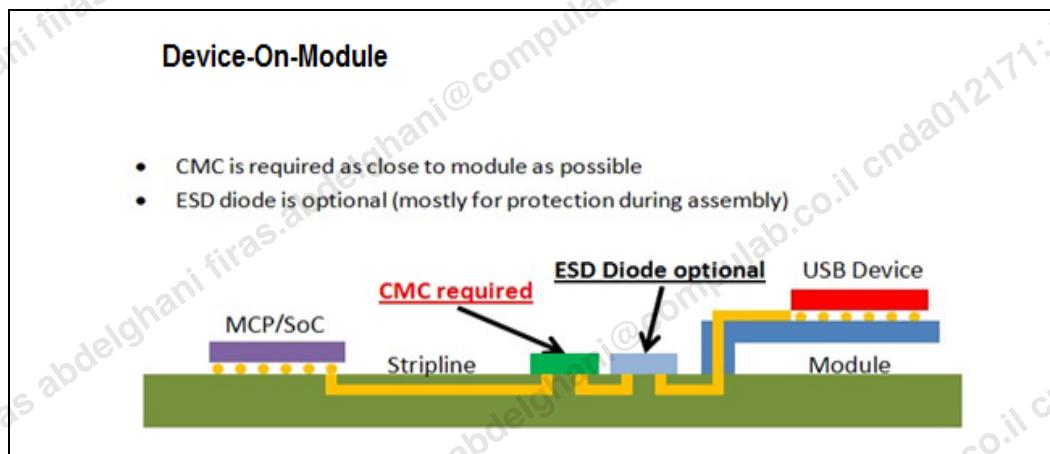
18.1.8 USB 3.1 Disabling and Termination Guidelines

- If some of the USB 3.1 port(s) are not implemented on the platform, USB3Tp/n [x] and USB3Rp/n [x] signals may be left unconnected, where 'x' is the port number left no connect.

18.1.8.1 Motherboard-down USB Devices

Note:

Intel recommends that USB 2.0 motherboard-down devices be routed to USB 2.0 connectors that are not paired with USB 3.1 signals to allow the USB 3.1 pairs to be used with SuperSpeed devices.

**Figure 18-8. Device-Down****Figure 18-9. Device-On-Module**

18.1.8.2 External End User Accessible Ports

Designers are recommended to provide a combination of USB 2.0 only ports and USB 3.1 ports for external use on their platforms to provide the greatest amount of flexibility for legacy device support.

18.1.8.3 USB Debug Port

The xHCI controller provides a debug port capability on all USB 3.1 ports.

§ §



19

Universal Serial Bus 2.0 Design Guidelines

Platform Controller Hub (PCH) has an xHCI controller and device controller implemented in it.

Table 19-1. USB 2.0 Reference Documents

Title	Doc #/Location
Front Panel I/O Connectivity Design Guide	http://www.formfactors.org/developer/specs/A2928604-005.pdf

Table 19-2. USB 2.0 Compliancy Documents

Title	Doc #/Location
USB 2.0 Specification and Compliancy Requirements	www.usb.org

19.1 USB 2.0 Signal Groups

Table 19-3. USB 2.0 Signal Groups

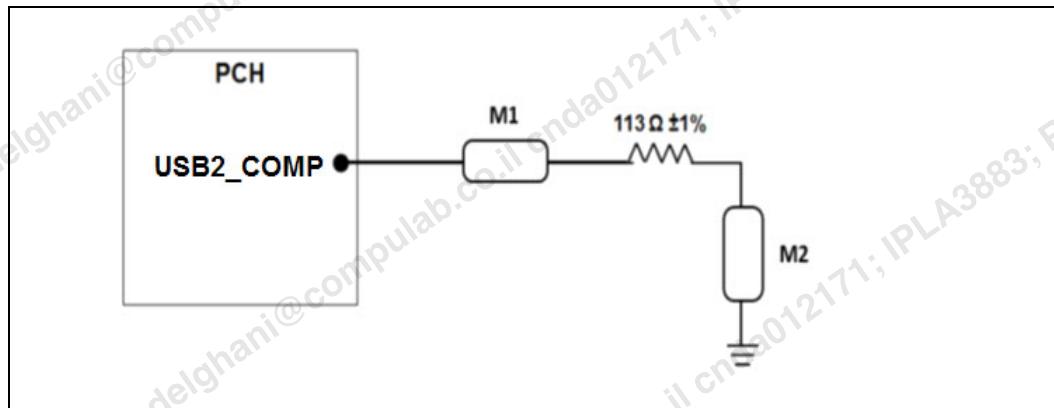
Group	Signal Name	Description
DATA	USB2P USB2N	Universal Serial Bus Port Differential Pairs.
OVERCURRENT	USB2_OC [7:0]#	Overcurrent Indicators
BIAS	USB2_COMP	Resistor Bias
Note: The supported connectors are Type A Dual Stack and Type A Single Stack. The connectors must meet the USB2.0 Connector Specification.		

19.2 USB2_COMP Topology

- The compensation input is used by the circuitry to determine, check and adjust the system buffer output strength and characteristic impedance over temperature, process and voltage variations. This is done comparing its buffer impedance against a standard reference resistor, RCOMP.

Note:

The USB2_COMP signals should be referenced to VSS, avoiding noisy or switching references. As board space allows, recommend to add a VSS shield at least 4 mils wide placed between USB2_COMP and adjacent IO

**Figure 19-1. USB2_COMP Connection**

19.3 USB2_COMP Routing Guidelines

Table 19-4. USB2_COMP Routing Guidelines

Signal	Trace Width (W) and Isolation Spacing (S)	Resistor Value	Length
USB2_COMP	No hard value for trace width and isolation spacing as long as DCR is met Though a baseline of using a 50Ω single ended channel is recommended. Note: must maintain low DC resistance routing ($< 0.5\Omega$) Note: a recommendation is to route the signal between 4-8 mils trace width for <1000 mils to meet DCR	$113 \Omega \pm 1\%$ connected to GND	M1/M1' + M2 No hard value for max length as long as DCR is met. However it is recommended to route these signals to a maximum of <1000 mils

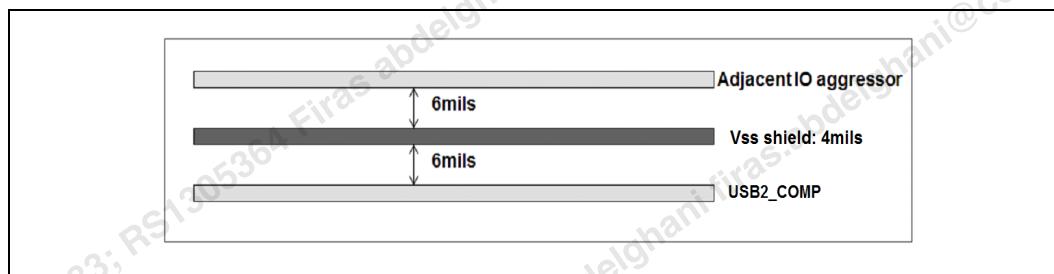
Note:

1. Although there is no hard value for max topology length as long as the DC resistance routing spec is met, although it is recommended to route the USB2_COMP as short as possible; a general recommendation is to maintain a length of <1000 mils, which will make it easier to hit the targeted DCR.

19.4 USB2_COMP to Other Interfaces

If unable to implement a Vss shield for USB2_COMP, the minimum spacing between USB2_COMP and other traces should be at least 15 mils to provide proper isolation.

If Vss shielding is implemented, then the spacing guideline in the figure below should be followed:

Figure 19-2. Spacing Guideline for USB2_COMP

19.5

Overcurrent Protection

Platform Controller Hub (PCH) has implemented programmable USB Overcurrent signals. The 7 overcurrent pins are to be shared across the USB 2.0 ports and USB 3.1 ports. This allows the platform designer flexibility in routing of the OC pins and allows for unused pins to be configured as GPIOs.

When configured for overcurrent protection, each of the OC pins needs to be connected to an external over current protection circuit. It is important to choose the correct current rating for the thermistor. Each USB port may draw up to 500 mA. The overcurrent protection circuitry needs to be able to support at least 2 A to ensure proper functionality of USB compliant devices. However, if a fault device is plugged into the USB port, it should trigger an overcurrent when current is more than 500 mA is drawn. Designer must balance between optimum cost and protection level.

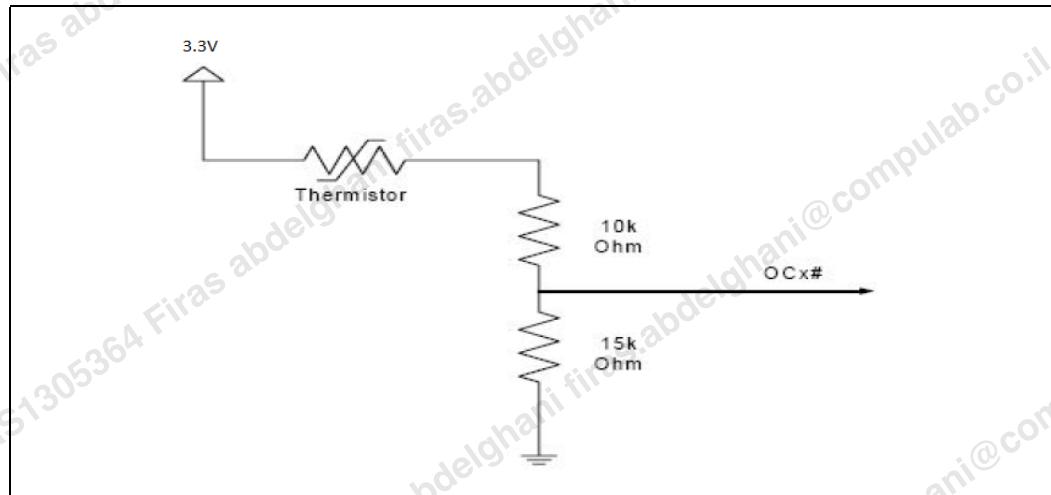
Notes:

1. When the current rating of the protection circuit has been decided, it is crucial to ensure that the overcurrent layout is designed to support the amount of current expected.
2. The overcurrent circuit should be designed to support up to 2 A, the overcurrent trace layout should be using a big fat trace or plane that can sustain at least 2 A.

Warning:

1. Failure to design the trace to support high current may cause the trace on motherboard to burn out and cause permanent damage to the protection circuit.
2. The overcurrent signals require a pull-up to the 3.3 V Suspend Rail with 8.2–10 K Ω resistor (refer figure below).

Figure 19-3. Sample Overcurrent Protection Circuit



The default configuration of the OC pins is in the table below. Each overcurrent pin is configured to protect one or more USB ports by setting bits in the U2OCM1 register in the xHCI controller.

Note:

It is the responsibility of system software (BIOS) to program the overcurrent registers of the given USB controller correctly and to make sure that each USB port is protected



by only one overcurrent pin. Operation with more than one overcurrent pin mapped to a port is undefined.

19.5.1 Overcurrent Pin Mapping

It is not recommended that customers map more than four USB ports to a single OC pin. Refer to PCH EDS for more details. Please follow PCH EDS on how to map OC pins to USB ports.

19.6 Integrated Bluetooth* and USB 2.0 Design Considerations

Due to the USB 2.0 port requirement for integrated Bluetooth* functionality with the Intel® Wireless-AC (CNVi) solution, Cannon Lake PCH-H USB 2.0 port # 14 will be available for the following platforms:

- **Coffee Lake H Platform**
 - USB 2.0 port 14 will be available for BT functionality only if Integrated Wireless solution is desired on CFL S Platform

If integrated Bluetooth* functionality is not desired, Cannon Lake PCH-H USB 2.0 port 14 may be used for USB functionality.

19.7 USB 2.0 Topology Guidelines

19.7.1 Back Panel/External Topology

The external topology refers to the routing of USB signals to a standard USB A connector. It is recommended that each USB data line be routed with a common mode choke and ESD protection.

Figure 19-4. USB 2.0 External Topology

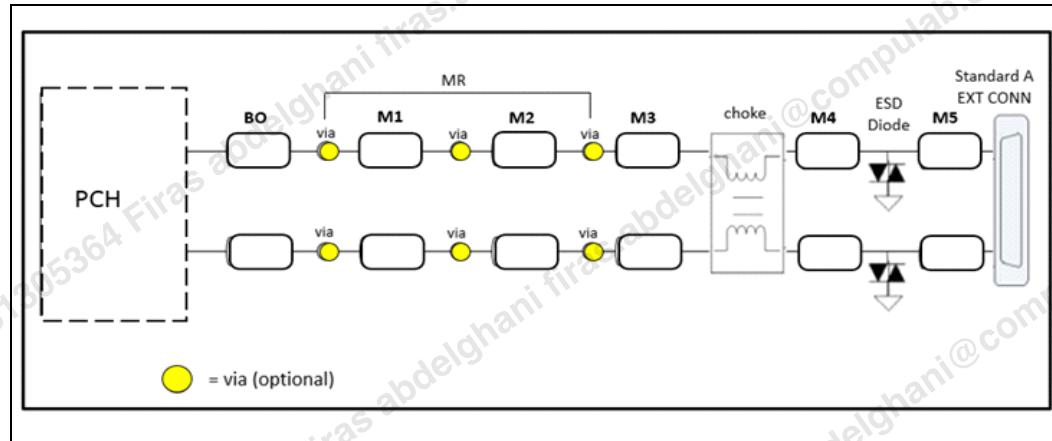


Table 19-5. USB 2.0 External Topology

Parameter	Segment	Stackup (MS/SL/ DSL)	Via Count	Reference	Routing Recommendations	
					Segment (mm)	Segment (mils)
Trace Length (MCP Breakout) Max	BO	MS /SL /DSL	1	VSS	15.2	598.42
Trace Length (Main route) Max	M1+M2	MS /SL /DSL	1	VSS	N/A	N/A
Trace Length (To Choke) Max	M3	MS	1	VSS	3.8	149.6
Trace Length (To ESD Diode) Max	M4	MS	0	VSS	3.8	149.6
Trace Length (To Connector) Max	M5	MS	0		12.7	500
Total Motherboard Trace Length	BO + M1 + M2 + M3 + M4 + M5			NA	Max = 304.8 Min = 76.2	Max = 12000 Min = 3000

Notes:

- Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils).
- Number of vias allowed is maximum of 3.
- Continuous GND referencing plane is preferred.
- In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line.

19.7.2 On-The-Go Topology

The On-The-Go topology refers to the routing of USB signals to a uAB connector. It is recommended that each USB data line be routed with a common mode choke and ESD protection.

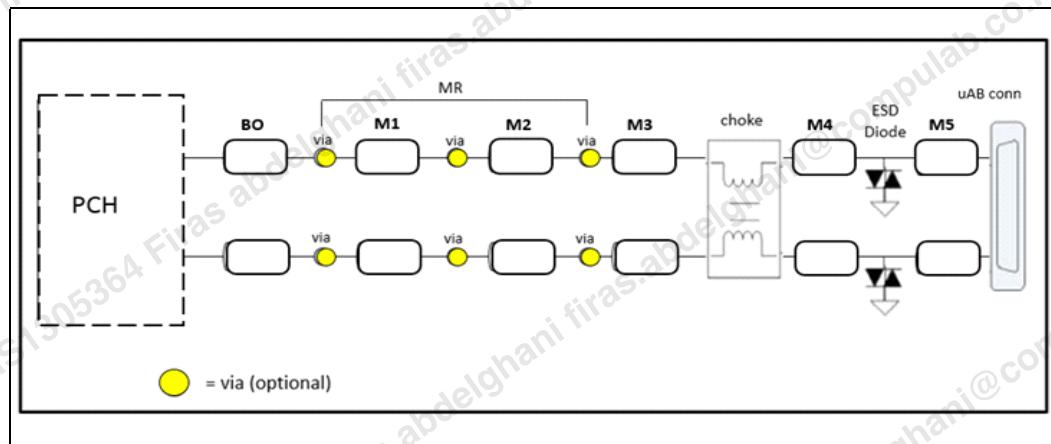
Figure 19-5. USB On-The-Go Topology


Table 19-6. USB 2.0 On-The-Go Topology

Parameter	Segment	Stackup (MS/SL/ DSL)	Via Count	Reference	Routing Recommendations	
					Segment (mm)	Segment (mils)
Trace Length (MCP Breakout) Max	BO	MS /SL /DSL	1	VSS	15.2	598.42
Trace Length (Main route) Max	M1+M2	MS /SL /DSL	1	VSS	N/A	N/A
Trace Length (To Choke) Max	M3	MS	1	VSS	3.8	149.6
Trace Length (To ESD Diode) Max	M4	MS	0	VSS	3.8	149.6
Trace Length (To Connector) Max	M5	MS	0		12.7	500
Total Motherboard Trace Length	BO + M1 + M2 + M3 + M4 + M5			NA	Max = 304.8 Min = 76.2	Max = 12000 Min = 3000

Notes:

- Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils).
- Number of vias allowed is maximum of 3.
- Continuous GND referencing plane is preferred.
- In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line.

19.7.3 USB 2.0 with M.2 Topology

The USB 2.0 with M.2 topology refers to the routing of USB signals to a standard M.2 connector. It is recommended that each USB data line be routed with a common mode choke.

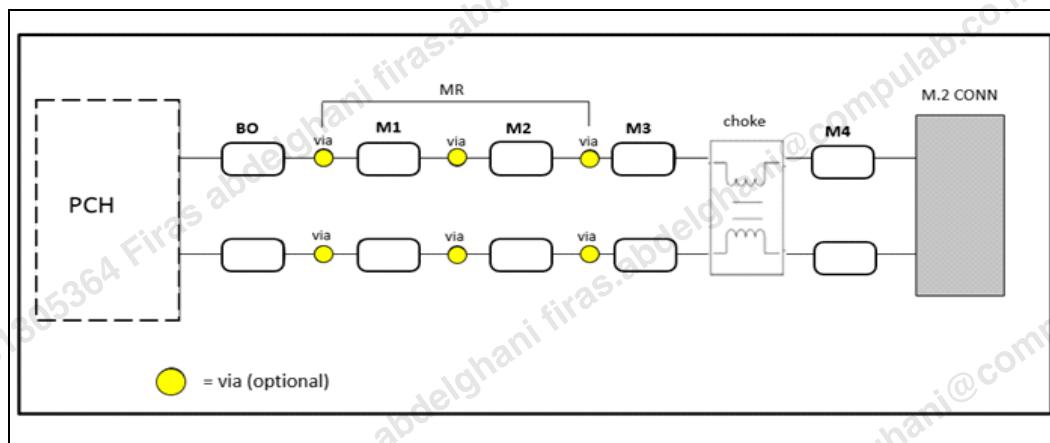
Figure 19-6. USB 2.0 with M.2 Topology

Table 19-7. USB 2.0 with M.2 Topology

Parameter	Segment	Stackup (MS/SL/ DSL)	Via Count	Reference	Routing Recommendations	
					Segment (mm)	Segment (mils)
Trace Length (MCP Breakout) Max	BO	MS /SL /DSL	1	VSS	15.2	598.42
Trace Length (Main route) Max	M1+M2	MS /SL /DSL	1	VSS	N/A	N/A
Trace Length (To Choke) Max	M3	MS	1	VSS	3.8	149.6
Trace Length (To ESD Diode) Max	M4	MS	0	VSS	12.7	500
Total Motherboard Trace Length	BO+ M1 + M2 + M3 + M4			NA	Max = 304.8 Min = 76.2	Max = 12000 Min = 3000

Notes:

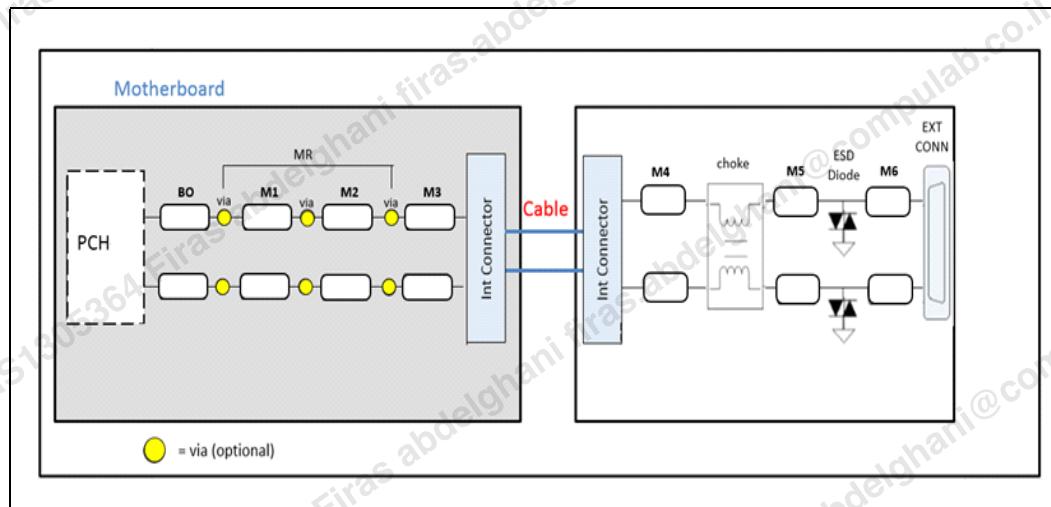
- Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils).
- Number of vias allowed is maximum of 3.
- Continuous GND referencing plane is preferred

19.7.4 USB 2.0 Flex/Internal Cable Topology

This topology supports a low profile internal connector, internal cable solution and a daughter card. It is recommended that each USB data line be routed with a common mode choke and ESD diode.

Note:

The Internal cable guidelines will be defined using insertion loss budget rather than cable length where a recommended mobile internal cable has a loss of 2 dB @ 2.5 GHz.

Figure 19-7. USB 2.0 Flex/Internal Cable Topology with Daughter Card


Design Constraint: Differential vias, CMC, ESD and connector voiding (strongly recommended) are required to optimize impedance mismatch in the channel.

**Table 19-8. USB 2.0 Flex/Internal Cable Topology with Daughter Card**

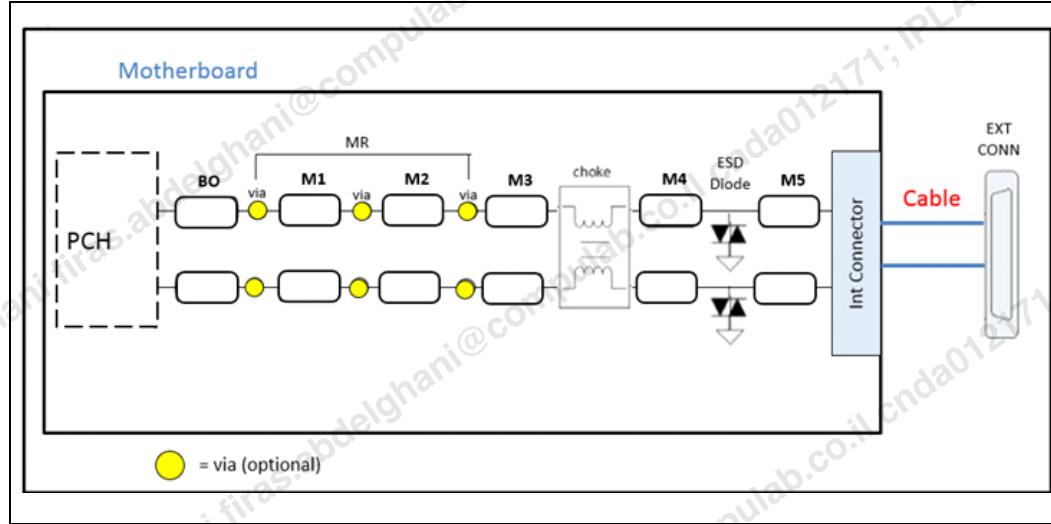
Parameter	Segment	Stackup (MS/ SL/ DSL)	Reference	Via Count	Routing Recommendations	
					Segment (mm)	Segment (mils)
Trace Length (MCP Breakout) Max	BO	MS /SL / DSL	VSS	1	15.2	598.42
Trace Length (Main route) Max	M1+M2	MS /SL / DSL	VSS	1	N/A	N/A
Trace Length (To Connector) Max	M3	MS	VSS	0	12.7	500
Trace Length (To Choke) Max	M4	MS	VSS	0	N/A	N/A
Trace Length (To Diode) Max	M5	MS	VSS	0	3.8	149.6
Trace Length (To Ext. Connector) Max	M6	MS	VSS	0	12.7	500
Total Motherboard Trace Length	BO+ M1 + M2 + M3	NA			Max = 152.4 Min = 76.2	Max = 6000 Min = 3000
Total Daughter Card Trace Length	M4 +M5 + M6	NA			Max = 50.8	Max = 2000

Notes:

- Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils).
- Number of vias allowed is maximum of 3.
- Continuous GND referencing plane is preferred.
- In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line.

Table 19-9. USB 2.0 Internal Cable Differential Insertion Loss Restrictions

Motherboard Total Trace Length (mm)	Motherboard Total Trace Length (Inches)	Maximum Daughter Card Trace Length (mm)	Motherboard Total Trace Length (Inches)	Internal Cable Assembly Insertion Loss Recommendation up to 2.5 GHz (dB)
152.4	6.0	50.8	2	2.0
139.7	5.5	50.8	2	2.0
127	5.0	50.8	2	2.5
114.3	4.5	50.8	2	3.0
101.6	4.0	50.8	2	3.5
89	3.5	50.8	2	3.5
76.2	3.0	50.8	2	4.0

Figure 19-8. USB 2.0 Flex/Internal Cable Topology without Daughter Card

Table 19-10. USB 2.0 Flex/Internal Cable Topology without Daughter Card

Parameter	Segment	Stackup (MS/ SL/ DSL)	Reference	Via Count	Routing Recommendations	
					mm	mils
Trace Length (MCP Breakout) Max	BO	MS / SL / DSL	VSS	1	15.2	598.42
Trace Length (Main route) Max	M1+M2	MS / SL / DSL	VSS	1	N/A	N/A
Trace Length (To Connector) Max	M3	MS	VSS	1	3.8	149.6
Trace Length (To Choke) Max	M4	MS	VSS	0	3.8	149.6
Trace Length (To Diode) Max	M5	MS	VSS	0	12.7	500
Total Motherboard Trace Length	BO+ M1 + M2 + M3+M4+M5	NA			Max = 177.8 Min = 76.2	Max = 7000 Min = 3000

Notes:

- Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils).
- Number of vias allowed is maximum of 3.
- Continuous GND referencing plane is preferred.
- In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line.

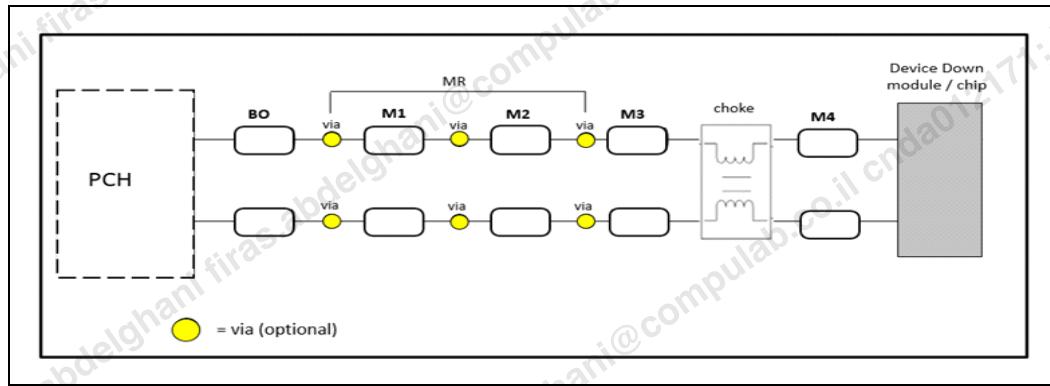
Table 19-11. USB 2.0 Internal Cable Differential Insertion Loss Restrictions (Sheet 1 of 2)

Motherboard Total Trace Length (mm)	Motherboard Total Trace Length (Inches)	Internal Cable Assembly Insertion Loss Recommendation up to 2.5 GHz (dB)
177.8	7.0	2.0

Table 19-11. USB 2.0 Internal Cable Differential Insertion Loss Restrictions (Sheet 2 of 2)

Motherboard Total Trace Length (mm)	Motherboard Total Trace Length (Inches)	Internal Cable Assembly Insertion Loss Recommendation up to 2.5 GHz (dB)
165.1	6.5	2.0
152.4	6.0	2.5
139.7	5.5	3.0
127	5.0	3.5
114.3	4.5	3.5
101.6	4.0	4.0
76.2	3.0	4.0

19.7.5 USB 2.0 Device Down Topology

Figure 19-9. USB 2.0 Device Down Topology**Table 19-12. Routing Guidelines for USB 2.0 Device Down Topology**

Parameter	Segment	Stackup (MS/SL/DSL)	Via Count	Reference	Routing Recommendations	
					Segment (mm)	Segment (mils)
Trace Length (MCP Breakout) Max	BO	MS / SL / DSL	1	VSS	15.2	598.42
Trace Length (Main route) Max	M1+M2	MS / SL / DSL	1	VSS	N/A	N/A
Trace Length (To Choke) Max	M3	MS	1	VSS	3.8	149.6
Trace Length (To ESD Diode) Max	M4	MS	0	VSS	12.7	500
Total Motherboard Trace Length	BO + M1 + M2 + M3 + M4 + M5			NA	Max = 304.8 Min = 76.2	Max = 12000 Min = 3000

Notes:

- Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils).
- Number of vias allowed is maximum of 3.
- Continuous GND referencing plane is preferred.
- In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line.

19.7.6

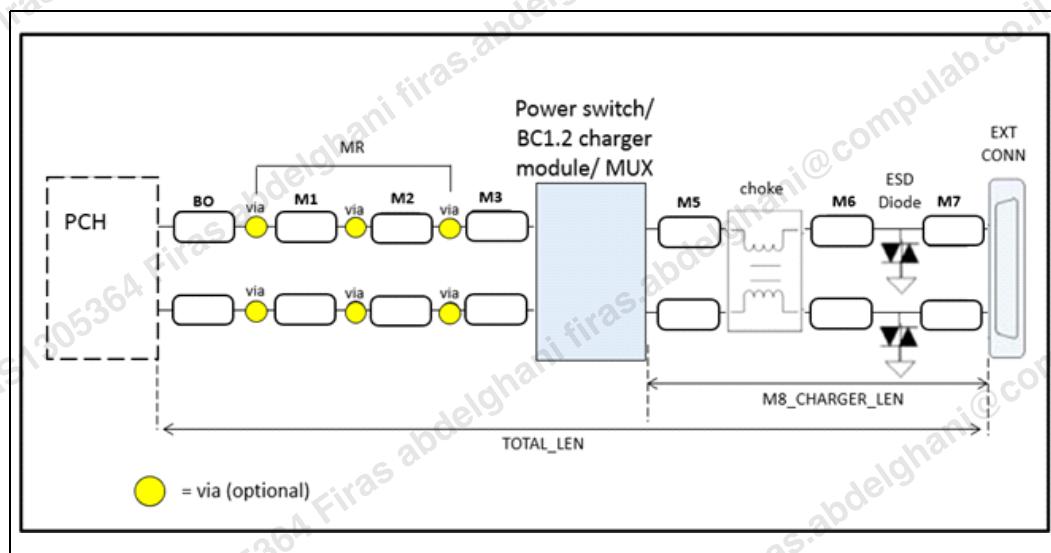
USB 2.0 External / Back Panel with Power Switch / BC1.2 Charger Module / MUX Topology

The external topology refers to the routing of USB 2.0 signals to a standard USB A connector. It is recommended that each USB data line be routed with a common mode choke and ESD protection. A Power switch / BC1.2 charger controller/ MUX /USB PD (BC1.2 detection) module is present in the topology.

Notes:

1. Current electrical characteristic recommendation on Power switch/controller/MUX for charging is to have on-state resistance and on-state capacitance of no greater than $6\ \Omega$ and 6pF respectively.
2. Current electrical characteristic limitation on Power switch/controller/MUX for charging is insertion loss of no greater than $-0.6\ \text{dB}$ and return loss of no greater than $-13\ \text{dB}$.
3. For a maximum length channel of $6''$ – it is recommended that the length of M8_Charger_Length be $1''$ (1000 mils) for a $6''$ channel. But, typically as short as possible.
4. The total channel (including the MUX/BC1.2 charger/power switch module) insertion loss should not exceed $-2.95\ \text{dB}$ and return loss should not exceed $-8.5\ \text{dB}$.
5. The length of the main board channel can be increased by trading-off the insertion loss (at 240 MHz) and equivalent on-state resistance and on-state capacitance of the BC1.2 charger module/power switch/MUX. The maximum on-state resistance and on-state capacitance as well as insertion loss allowable for the module is dependent on the total board routing as shown in USB2.0 BC1.2 / MUX/ Power switch Component Restrictions.

Figure 19-10.USB 2.0 External / Back Panel with Power Switch/ BC1.2 Charger Module/ MUX Topology



**Table 19-13. USB 2.0 External / Back Panel with Power Switch / BC1.2 Charger Module / Mux Topology Routing Guidelines**

Parameter	Segment	Stackup (MS/SL/DSL)	Reference	Via Count	Routing Recommendations	
					Segment (mm)	Segment (mils)
Trace Length (MCP Breakout) Max	BO	MS /SL / DSL	VSS	1	15.2	598.42
Trace Length (Main route) Max	M1+M2	MS /SL / DSL	VSS	1	N/A	N/A
Trace Length (To BC1.2 Charger/ Mux) Max	M3	MS	VSS	1	3.8	149.6
Trace Length (To Choke) Max	M5	MS	VSS		N/A	N/A
Trace Length (To ESD Diode) Max	M6	MS	VSS	1	3.8	149.6
Trace Length (To Ext. Connector) Max	M7	MS	VSS	0	12.7	500
M8_chareger_Length Max	M5 + M6 + M7 (M8_charger_len)	MS	VSS	0	25.4	1000
Total Motherboard Trace Length	BO+ M1 + M2 + M3 + M4	NA			Max = 152.4 Min = 76.2	Max = 6000 Min = 3000
Notes:						
<ol style="list-style-type: none"> Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils). Number of vias allowed is maximum of 3. Continuous GND referencing plane is preferred Typical component R/C:ON-state resistance and capacitance of 6ohm and 6pF, Insertion Loss <= -0.6dB ; Return Loss <= -13dB Total channel insertion and return loss: Insertion Loss <= -3dB ; Return Loss <= -8.5dB. In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line. 						

Table 19-14. BC1.2 Charger Controller/MUX/Power switch/USB PD (with BC1.2 detection) Module Component Restrictions

Motherboard Total Trace Length (mm)	Motherboard Total Trace Length (Inches)	Max charger module on-state resistance, Ron (Ω); on-state capacitance, Con (pF)	Equivalent charger module insertion loss (dB) at 240 MHz
177.8	7.0	4 Ω 4 pF	-0.45 to 0.46 dB
152.4	6.0	5 Ω 5 pF	-0.57 to 0.58 dB
127	5.0	6 Ω 6 pF	-0.74 to 0.75 dB
101.6	4.0	6 Ω 6 pF	-0.74 to 0.75 dB
76.2	3.0	7 Ω 7pF	-0.88 to 0.89 dB

19.7.7 USB 2.0 Docking Topology

- Total trace length will influence the USB transmit amplitude setting. USB Initialization Registers can be set according to recommendations available in Cannon Lake PCH-H External Design Specification.
- This topology meets USB 2.0 specifications if a trace length on the motherboard (M_MB_LEN) is >4" and the length of M1 ≠ M2. At very short motherboard lengths of 3-4" with M1 = M2 is this topology may not meet the USB 2.0 electrical

specifications. Using a dock with integrated USB Hub may increase the routability of this topology.

- It is recommended that each USB data line be routed with a common mode choke and ESD diode

Note: Via placement is compensable. If vias are not used on the main motherboard, then additional via can be placed on the docking board and vice versa. However, total number of vias in entire channel is 3.

Figure 19-11.USB 2.0 Traditional Docking Topology

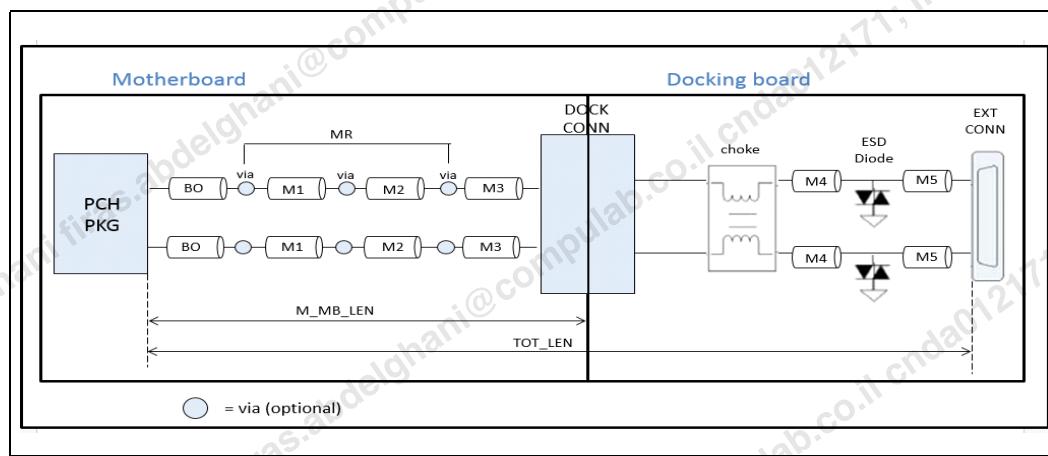


Table 19-15. USB 2.0 Traditional Docking Topology Routing Guidelines

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length,Mils			
				Segment	Total	Segment	Total		
BO	MS/SL/DSL	VSS	1	15.2	76.2 (min) 254 (max)	598.42	3000 (min) 10000 (max)		
M3	MS	VSS	1	3.8		149.6			
M4	MS	VSS	0	3.8		149.6			
M5	MS	VSS	0	12.7		500			
M1+M2	MS/SL/DSL	VSS	1	N/A		N/A			
Notes:									
1. Length Matching between P and N with in a differential pair with in same layer mismatch is +/-0.254mm (+/-10mils). Total length mismatch is +/-0.381mm (+/-15mils).									
2. Number of vias allowed is maximum of 3.									
3. Continuous GND referencing plane is preferred									
4. General Docking Routing: $0.3 < M_MB_LEN / TOT_LEN < 0.8$, $M1 = M2$ and $M_MB_LEN > 3"$.									
5. In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line.									

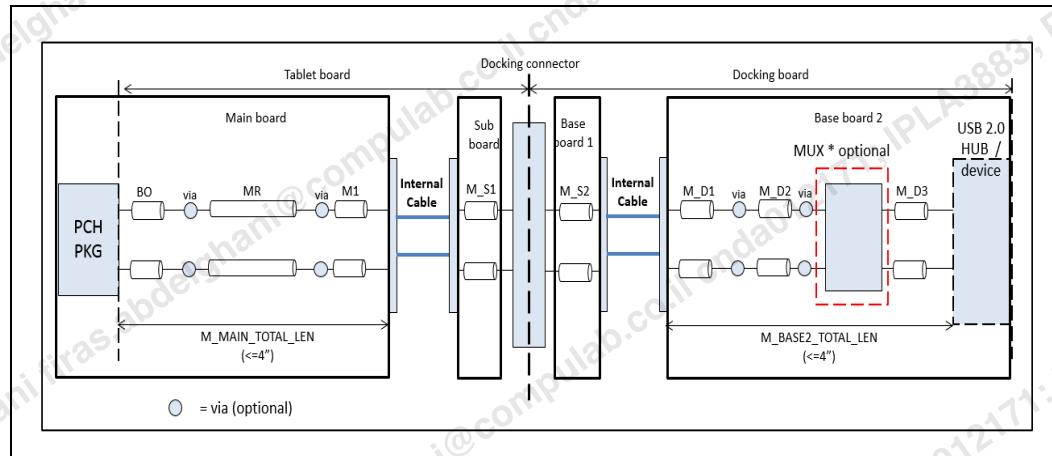
19.7.8 USB 2.0 Detachable Docking Topology

The following figure shows and overview of the docking topology which supports routing from the PCH on the motherboard to a USB 2.0 A-connector on a docking board. Careful attention should be given to the docking connector design as well as its associated internal cables and sub/base boards to ensure that signal quality is not degraded. A USB 2.0 Hub is required on the docking board. Since different Hub chips



have different characteristics, contact your Hub Vendor for routing guidelines from the Hub to A-connector. It is recommended that each USB data line be routed with a common mode choke and ESD protection from the Hub to A-connector

Figure 19-12.USB 2.0 Detachable Docking Topology



Note:

Single multiplexer (MUX) on the docking board is optional and is required if a flippable dual-side detachable docking connector is required. Mux component should have an on-state resistance and on-state capacitance of not more than $6\ \Omega$ and $6\ pF$ (which translates to an insertion loss of roughly $-0.74\ dB$).

In order to assure adequate EMI and ESD protection, a common mode choke and ESD protection diode should be implemented on each USB data line.

Table 19-16.USB 2.0 Detachable Docking Routing Guidelines

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length,Mils							
				Segment	Total	Segment	Total						
BO	MS/SL/DSL	VSS	0	15.2	50.8 (min) 101.6 (max)	598.42	2000 (min) 4000 (max)						
M1	MS	VSS	1	3.8		149.6							
MR	MS/SL/DSL	VSS	1	N/A		N/A							
M_S1	MS/SL/DSL	VSS	0	25.4	25.4	1000	1000						
M_S2	MS/SL/DSL	VSS	0	25.4	25.4	1000	1000						
M_D1	MS	VSS	1	3.8	54.6 (min) 105.4 (max)	149.6	2149.6 (min) 4149.6 (max)						
M_D2	MS/SL/DSL	VSS	1	50.8		2000							
M_D3	MS/SL/DSL	VSS	0	50.8		2000							
Notes:													
1. Length Matching between P and N with in a differential pair with in same layer mismatch is $+/-0.254mm$ ($+/-10mils$). Total length mismatch is $+/-0.381mm$ ($+/-15mils$).													
2. Number of vias allowed is maximum of 4.													
3. Continuous GND referencing plane is preferred													

**Table 19-17. USB 2.0 Trade-off on Internal Cable Differential Insertion Loss on Margins**

Main Board Total Trace Length (mm)	Main Board Total Trace Length (Inch)	Internal Cable Assembly Insertion Loss on Tablet/motherboard	Internal Cable Assembly Insertion Loss on Docking
101.6	4.0	.43 dB (at 240 MHz) [2.2 dB at 2.5 GHz]	.43 dB (at 240 MHz) [2.2 dB at 2.5 GHz]
88.9	3.5	.52 dB (at 240 MHz) [2.76 dB at 2.5 GHz]	.52 dB (at 240 MHz) [2.76 dB at 2.5 GHz]
76.2	3.0	.61 dB (at 240 MHz) [3.34 dB at 2.5 GHz]	.61 dB (at 240 MHz) [3.34 dB at 2.5 GHz]
63.5	2.5	.69 dB (at 240 MHz) [3.73 dB at 2.5 GHz]	.69 dB (at 240 MHz) [3.73 dB at 2.5 GHz]
50.8	2.0	.76 dB (at 240 MHz) [4.24 dB at 2.5 GHz]	.76 dB (at 240 MHz) [4.24 dB at 2.5 GHz]

Consider the following guidelines:

- Total trace length will influence the USB transmit amplitude setting. USB Initialization Registers can be set according to recommendations available in the *Cannon Lake PCH-H External Design Specification*.
- This topology meets USB 2.0 specifications if a trace length on the motherboard (`M_MB_LEN`) is >4" and the length of `M1` ≠ `M2`. At very short motherboard lengths of 3-4" with `M1` = `M2` is this topology may not meet the USB 2.0 electrical specifications. Using a dock with integrated USB Hub may increase the routability of this topology.

Notes:

- Via placement is compensable. If vias are not used on the main motherboard, then additional via can be placed on the docking board and vice versa. However, total number of vias in entire channel is 3.

19.7.9 USB Connector Recommendations

Proper connector choice is critical to ensure adequate USB signal quality. Empirical data has shown that quad-stack USB and DisplayPort*/USB stack connectors may add interference causing poor USB signal quality. Refer to usb.org for a list of tested connectors.

19.7.9.1 External Connector Recommendations

The cable and PCB mating connector must pass the TDR requirements listed in the USB 2.0 Specification.

USB 2.0 Mobile Internal Connector

It is possible to define the internal connector pin list based on individual needs. However, an example connector pin list for 2-port internal cable connection supporting both USB 2.0 and USB 3.1 is shown in the following table.

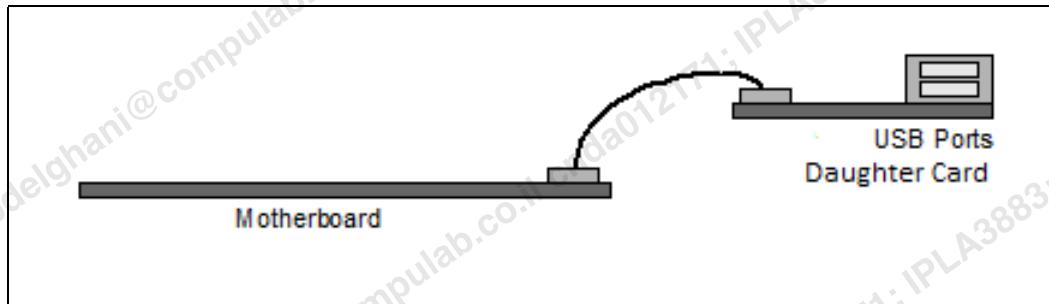
**Table 19-18. Example of Internal Connector Pin Assignment and Description**

Pin Number	Signal	Description
1	RSVD	Reserved Pin
2	Vbus	5 v bus power
3	Vbus	5 V bus power
4	Vbus	5 V bus power
5	USB2_DIP	USB 2.0 Port 1 D-
6	USB2-DIN	USB 2.0 Port 1 D+
7	PWR_GND	Power GND return
8	USB2_D2P	USB 2.0 Port 2 D+
9	USB2_D2N	USB 2.0 Port 2 D-
10	PWR_GND	Power GND return
11	USB3_TX1P	USB 3.1 Port 2 SuperSpeed Tx+
12	USB3_TX1N	USB 3.1 Port 2 SuperSpeed Tx-
13	SIG_GND	Signal GND return
14	USB3_RX1P	USB 3.1 Port 2 SuperSpeed Rx+
15	USB3_RX1N	USB 3.1 Port 2 SuperSpeed Rx-
16	SIG_GND	Signal GND return
17	USB3_TX2P	USB 3.1 Port 2 SuperSpeed Tx+
18	USB3_TX2N	USB 3.1 Port 2 SuperSpeed Tx-
19	SIG_GND	Signal GND return
20	USB3_RX2P	USB 3.1 Port 2 SuperSpeed Rx+
21	USB3_RX2N	USB 3.1 Port 2 SuperSpeed Rx-
22	SIG_GND	Signal GND return

19.7.10 Daughter Card

The best way to provide internal support for USB is to use a daughter card and cable assembly. This allows the placement of the EMI/ESD suppression components right at the USB connector where they will be the most effective. The following figure shows the major components associated with a typical USB solution that uses a daughter card.

When designing the motherboard with internal topology support, the system integrator should know which type of cable assembly will be used. If the system integrator plans to use a connector card, ensure that there are not duplicate EMI/ESD/thermistor components placed on the motherboard, as this will usually cause drop/droop and signal quality degradation or failure.

Figure 19-13.Daughter Card

Daughter Card Design Guidelines

The followings are recommended when designing a USB 2.0 daughter card:

- Place the VBUS bypass capacitor, CMC, and ESD suppression components on the daughter card as close as possible to the connector pins.
- Follow the same layout, routing and impedance control guidelines as specified for motherboards.
- Use the same mating connector pinout as - USB 3.1 Internal Connector Pinout (Motherboard).
- Minimize the trace length on the daughter card - Less than a 2-inch trace length is recommended.
- Use the same routing guidelines as described in USB 2.0 Stack-up Guidelines.
- Power and ground nets should have double vias. Trace lengths should be kept as short as possible.

19.7.11 USB 2.0 Stack-up Guidelines

19.7.12 Stack-up and Layer Utilization Guidelines

Refer to [Chapter 2, "Stack-Up and PCB Considerations"](#) - Type 3 and Type 4 Stack-up sections for all I/O routing guidelines including USB 2.0.

19.7.13 USB 2.0 Configuration, Connectivity, Block Diagram

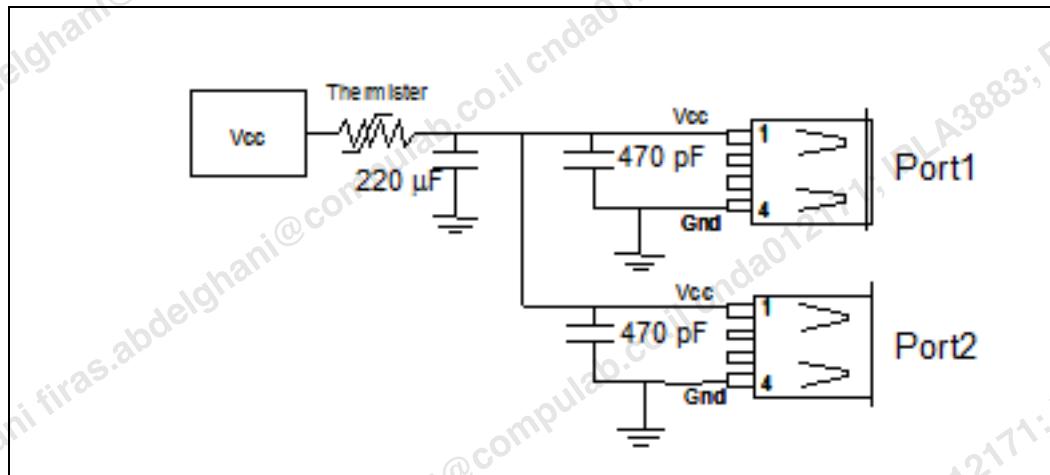
19.7.14 Port Power Delivery

The following is a suggested topology for power distribution of VBUS to USB ports. These circuits provide two types of protection during dynamic attach and detach situations on the bus: inrush current limiting (droop) and dynamic detach flyback protection. These two types require both bulk capacitance (droop) and filtering capacitance (for dynamic detach flyback voltage filtering). Intel recommends the following:

- Minimize the inductance and resistance between the coupling capacitors and the USB ports.
- Place capacitors close as possible to the port and the power-carrying traces should be as wide as possible, preferably, a plane.

- Make the power-carrying traces wide enough that the system fuse blows on an overcurrent event. If the system fuse is rated at 1 A, then the power-carrying traces should be wide enough to carry at least 1.5 A.

Figure 19-14. Good Downstream Power Connection



19.7.15 USB 2.0 Length Matching Guidelines

19.7.15.1 Length Matching

Refer to the [Section 3.4, "General Differential Length Matching Guidelines"](#) for length matching guidelines.

19.7.16 EMI and ESD Protection

Refer to [Chapter 49, "Electromagnetic Compatibility"](#)

19.7.17 USB 2.0 Disabling and Termination Guidelines

If a USB port(s) is not implemented on the platform:

- USB P/N [x] signals can be left unconnected

§ §



20 USB Type-C

USB Type-C is a cable and connector specification defined by USB-IF. The connector is defined so that it is capable of supporting ultra thin form factor with z height as low as 3mm and also enhanced user experience by allowing the USB Type-C plug to be plugged into a receptacle either right side up or up side down. Refer to the following figure for the detailed pin map of a USB Type-C receptacle.

Coffee Lake supports device role on all its USB ports. In Coffee Lake, the only way to put a port in device mode is by setting control register bits specific to USB port and not via hardware mechanism as in Kaby Lake (OTG_ID, VBUS_SENSE is used to detect in Kaby Lake).

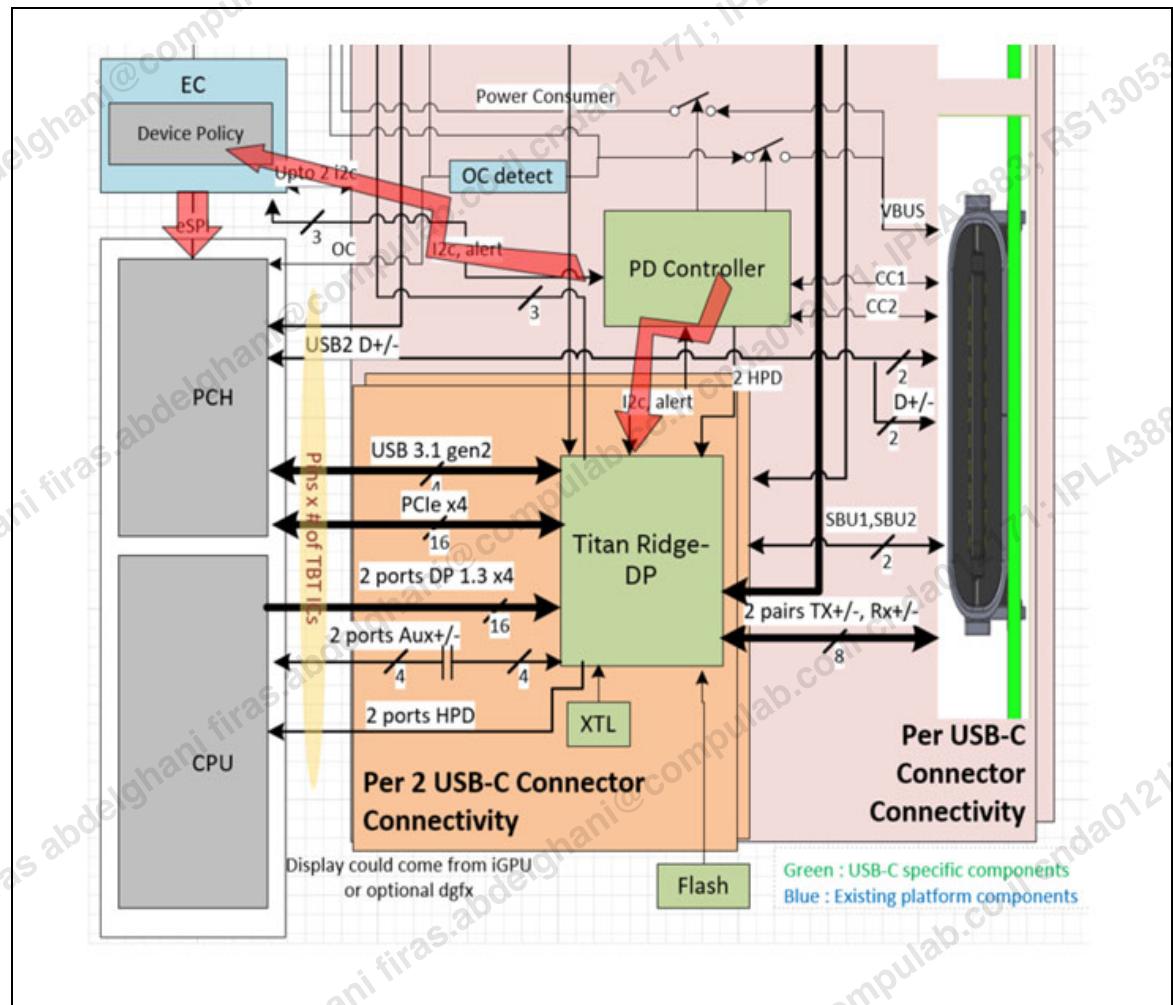
For USB type-A ports, which are host only ports, there is a strap in PCH to configure specific USB3 ports to be host only and in such cases PCH leaves USB3 ports connected to its internal logic. Since USB-C connector supports both host and device role, we cannot set that strap. When strap is not set, Coffee Lake SoC leaves the USB3 port disconnected from internal logic. This means at every connect/disconnect/role change events for USB-C, we need to explicitly communicate this information to the SoC. In addition to this, alternate mode entry/exit also need to be explicitly communicated to SoC since it has to know when USB3 is getting connected/disconnected vs both USB3/USB2 getting connected/disconnected.

Coffee Lake SoC supports 2 ways for this communication. This is new requirement for Coffee Lake.

1. eSPI messages between EC and PMC when eSPI EC is used.
2. BIOS to set control register bits when LPC EC is used. Since SoC needs to be in S0 when using BIOS mechanism, some of the low power/early boot scenarios will NOT be supported using LPC ECs.

During system state transitions, when EC remains powered ON but SPR registers inside PCH maybe reset, at that time it's responsibility for EC to resend connect messages for respective connectors to the PMC.

Figure 20-1. Coffee Lake Platform USB Type-C Block Diagram



Note:

The figure above is a high level example implementation block diagram for two USB Type-C connectors with Titan Ridge TBT and PD Controller. The red arrows indicate the communication pathways. Actual implementation on schematics may vary.

Figure 20-2. USB Type-C Receptacle Pin Map

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TX1+	TX1-	VBUS	CC1	D+	D-	SBU1	VBUS	RX2-	RX2+	GND
GND	RX1+	RX1-	VBUS	SBU2	D-	D+	CC2	VBUS	TX2-	TX2+	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

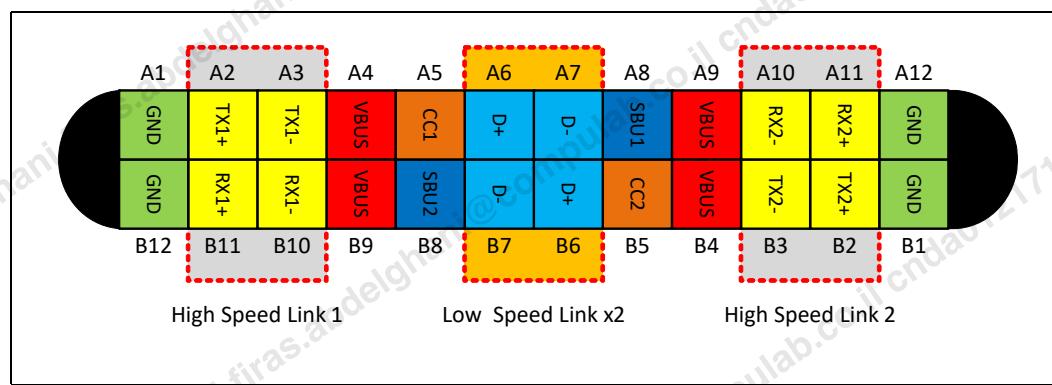
USB Type-C connector consists of 24 signal pins designed in a symmetrical way. Refer to Section 20.2, "USB Type-C Signal Group and Descriptions" for description of all the signals on a USB Type-C connector.

There are up to 6 differential pairs available on a USB Type-C connector, with 4 high speed different pairs and 2 low speed pairs. There are 2 configuration channel signals (CC1/CC2) on the connector which is used for:

- Device detection
- Orientation detection
- Establish DFP and UFP roles
- Discover and configure power
- Discover and configure optional alternate/accessory modes

Unused CC pin will be reconfigured as Vconn, which is used to power the active cable.

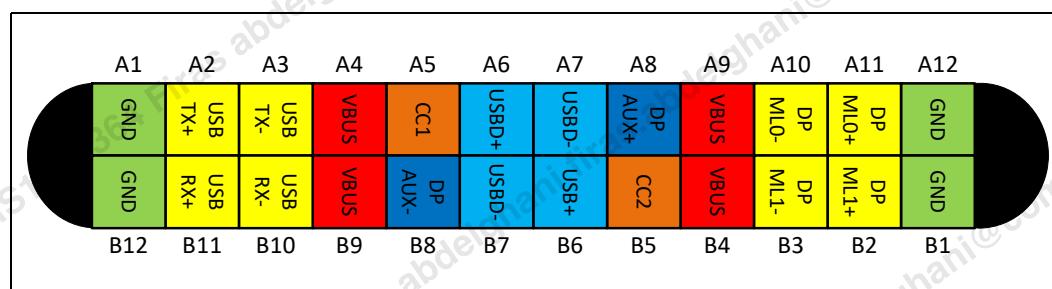
Figure 20-3. Anatomy of a USB Type-C Receptacle



With two configuration channel signals for communication, USB Type-C connector can support not only USB interfaces but also any other vendor specific interface like DisplayPort* in Alternate Mode.

In Alternate Mode, both the high speed and low speed link and both the SBU1/2 pins can be reconfigured to support the intended configuration. See figure below for an example of the pin re-configuration to support a USB + DP x 2 configuration. DP as an Alt Mode will be described in more detail in the later sections.

Figure 20-4. USB Type-C Connector Pin Map for a USB + DP x 2 Alternate Mode Example





20.1

USB Type-C Platform- Specific Important Information

Coffee Lake platform support USB Type-C implementation using TCPCi based port controller. USB Type-C port can be configured to support Alternate Modes as per the specification such as DisplayPort* by reconfiguring the connector pins.

Coffee Lake platform reference collateral provide sample implementation of various configuration options that the USB Type-C specification offers including USB 2.0/3.1 and Alternate Modes such as DisplayPort*.

Refer to table below for the supported features being enabled for the Coffee Lake platform.

Table 20-1. USB Type-C Supported Configuration on Coffee Lake

Interface 1	Interface 2	Interface3	Description
USB 3.1 SS			USB only with no Alternate Mode
USB 3.1 SS	DP* x 2		USB with DP 1.3. USB 3.1SS and DP x 2 can be active concurrently.
USB 3.1 SS	DP * x 4		USB with DP 1.3 for DP panel support with higher resolution. DP x 4 and USB 3.1 SS cannot exist concurrently. When DP x4 is active only USB 2.0 signal is available.
USB 3.1 SS	DP* x 2 or DP * x 4	Intel(R) DCI OOB	Intel(R) DCI OOB is supported over active switch

20.2

USB Type-C Signal Group and Descriptions

Group	Signal Name	Description
Power	VBUS	VBUS, capable of up to 3A @ 20V with USB PD
	VCONN	VCONN is a power source to active cable which is capable of supplying up to 0.2A @ 5V. Unconnected CC pin will be reconfigured to VCONN when a device is plugged in.
Ground	GND	Ground
High Speed Differential	TX1+	First USB3.1 Diff TX pair
	TX1-	
	RX1+	First USB3.1 Diff RX pair
	RX1-	
	TX2+	Second USB3.1 Diff TX pair
	TX2-	
	RX2+	Second USB3.1 Diff RX pair
Low Speed Differential	D+	Low Speed Differential Pair, primary for USB 2 connection
	D-	

Group	Signal Name	Description
Control	CC1	Configuration Channel 1. Used for device detection, orientation detection and Alternate Mode configuration. Unconnected pins will be reconfigured to Vconn.
	CC2	Configuration Channel 2.Used for device detection, orientation detection and Alternate Mode configuration. Unconnected pins will be reconfigured to Vconn
Side band	SBU1	Sideband signals for use by alternate mode AUX signals
	SBU2	

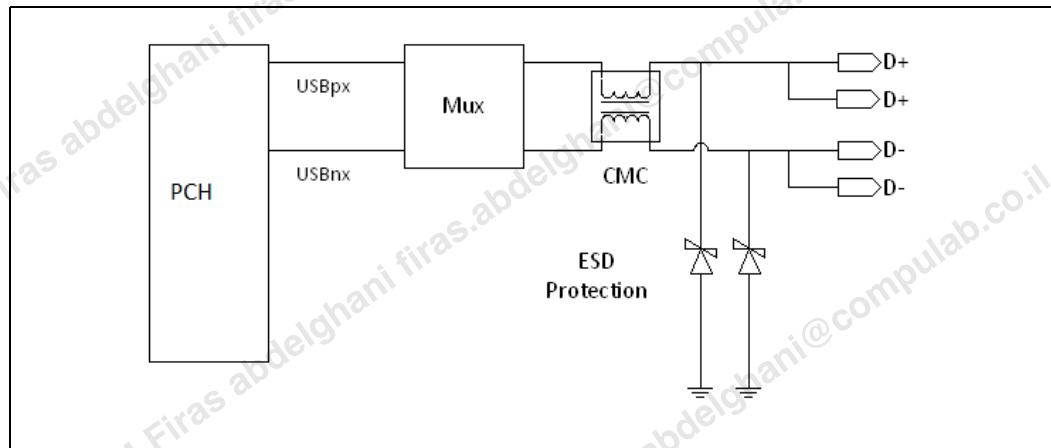
20.3 USB Type-C Topology Guidelines

20.3.1 USB 2.0 Guidelines

USB Type-C can be configured to support USB signals only (LS,FS,HS,SS) with a minimum requirement of USB 2.0 (LS, FS, HS) support. Below are the options available for implementing a USB only USB Type-C connector with discrete components on a Coffee Lake platform.

- USB 2.0 USB Type-C Topology
- USB 2.0 with BC1.2 charger module / MUX / Power Switch Topology.
- USB2.0 with MUX and Redriver topology

Figure 20-5. USB 2.0 Only USB Type-C Connector



Note:

The figure above is a high level example implementation block, actual implementation on the schematic may vary.

USB 2.0 is the minimum requirement for implementing a USB Type-C connector. This configuration is achieved by connecting a pair of USB 2.0 signal to DP+/DP- pins on the receptacle and shorting the 2 DP+/DP- on the receptacle together. On Coffee Lake, all ports are capable of supporting dual role but only one port at a time.

CC1/CC2 is no longer required to handle plug orientation detection in this configuration as there is no switching needed. However discrete CC logic is still needed for handling UFP/DFP detection, Vconn switching and VBUS control.

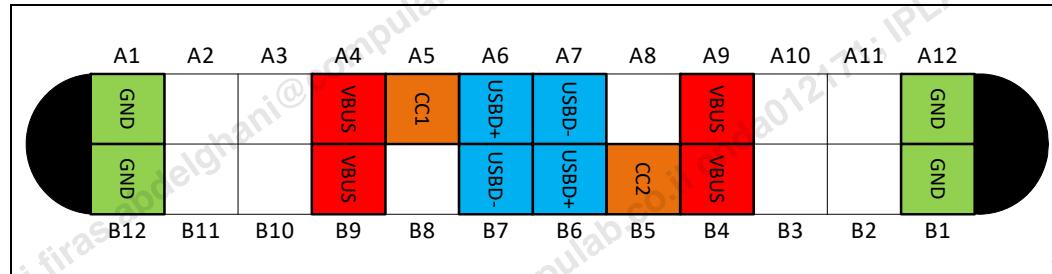


ESD protection devices is required for all signal connecting to Coffee Lake directly. For signals that is connected to 3rd party component like MUX/controller, refer to 3rd Party component specification to decide if platform level ESD device is needed.

CMC may be required to pass EMI test therefore a CMC footprint is recommended.

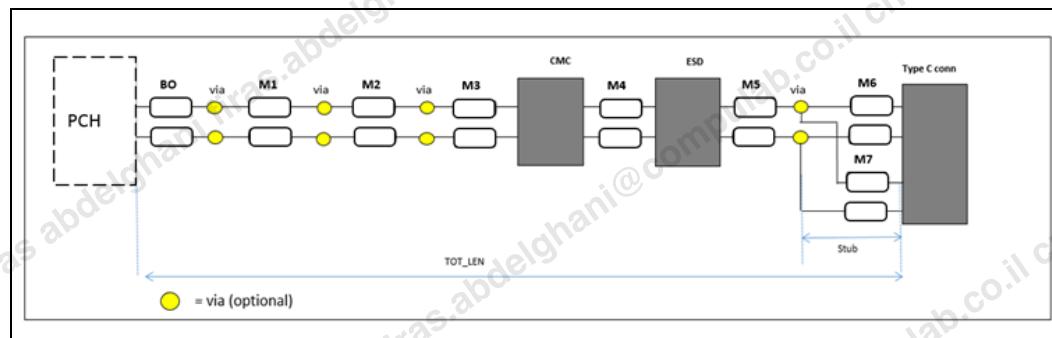
USB_ID and VBUS_SENSE pins are not needed for USB Type-C implementation with Type-C port controller (TCPC).

Figure 20-6. USB Type-C Receptacle Pin Map – USB 2.0 Only



20.3.1.1 Layout Guideline

Figure 20-7. USB 2.0 USB Type-C Topology



USB 2.0 USB Type-C Topology Routing Guidelines (Sheet 1 of 2)

Parameter	Segment	Stackup	Via Count	Length (mm)	Length (mils)
Trace Length Maximum	B0	MS/SL/DSL	1	15.2	598.42
Trace Length Maximum	M3	MS	1	3.8	149.6
Trace Length Maximum	M4	MS	0	3.8	149.6
Trace Length Maximum	M5	MS	0	14	551.18
Trace Length Maximum	M6	MS	1	3.6	141.73
Trace Length Maximum	M7	SL/DSL		3.6	141.73
Trace Length Maximum	M1+M2	MS/SL/DSL	1	NA	NA
Total Trace Length Minimum and Maximum	B0+M1+M2+M3+M4+M5+(M6 or M7)			76.2 (min) 228.6 (max)	3000 (min) 9000 (max)

USB 2.0 USB Type-C Topology Routing Guidelines (Sheet 2 of 2)

Parameter	Segment	Stackup	Via Count	Length (mm)	Length (mils)
Notes:					
1. Length Matching allowed between P and N within a differential pair: a. Within same layer mismatch: $\pm 0.254\text{mm}$ ($\pm 10\text{mils}$). b. Total length mismatch: $\pm 0.381\text{mm}$ ($\pm 15\text{mils}$). 2. Maximum via count is 4 ((including the one implemented to accommodate stub). 3. NA in the table implies that there is no strict trace length requirements for that particular segment. 4. Maximum stub length allowed is 3.6mm (141.7 mils) 5. Continuous GND referencing is preferred. Power plane referencing is also allowed.					

Figure 20-8. USB 2.0 with BC1.2 Charger Module / MUX / Power Switch Topology

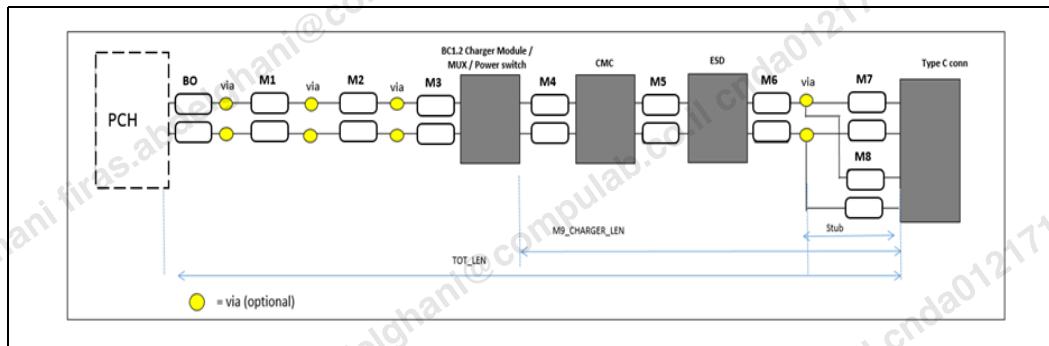


Table 20-2. USB 2.0 with BC1.2 Charger Module / MUX / Power Switch Topology Routing Guidelines

Parameter	Segment	Stackup	Via Count	Length (mm)	Length (mils)
Trace Length Maximum	B0	MS/SL/DSL	1	15.2	598.42
Trace Length Maximum	M1+M2	MS/SL/DS	1	NA	NA
Trace Length Maximum	M3 or M5	MS	1	3.8	149.6
Trace Length Maximum	M6	MS	0	14	551.18
Trace Length Maximum	M7	MS	1	3.6	141.73
Trace Length Maximum	M8	SL/DSL		3.6	141.73
Trace Length Maximum	M4+M5+M6+M7 or M4+M5+M6+M8 (M9 Charger Length)	MS	0	25.4	1000
Total trace length (min and max)				76.2 (min) 152.4 (max)	3000 (min) 6000 (max)

Notes:

- Length Matching allowed between P and N within a differential pair:
 - Within same layer mismatch: $\pm 0.254\text{mm}$ ($\pm 10\text{mils}$).
 - Total length mismatch: $\pm 0.381\text{mm}$ ($\pm 15\text{mils}$).
- Maximum number of vias allowed is 4 (including one implemented to accommodate stub).
- NA in the table implies that there is no strict trace length requirements for that particular segment.
- Reference plane recommended is continuous ground. Power plane referencing is also allowed.
- Maximum stub length allowed is 3.6mm (141.7 mils).
- Typical component R/C:
 - On-state resistance is 6 Ohm and capacitance is 6pF.
 - Insertion Loss $\leq -0.6\text{dB}$; Return Loss $\leq -13\text{dB}$.
- Total channel insertion and return loss:
 - Insertion Loss $\leq -3\text{dB}$; Return Loss $\leq -8.5\text{dB}$.

Figure 20-9. BC1.2 Charger Module / MUX / Power Switch/USB PD (with BC 1.2 detection) Module Component Restrictions

Motherboard Total Trace Length (mm)	Motherboard Total Trace Length (inches)	Max charger module on-state resistance, R_{on} (Ω) ; on-state capacitance, C_{on} (pF)	Equivalent charger module insertion loss (dB) at 240 MHz
177.8	7.0	4 Ω ; 4 pF	-0.45 to 0.46 dB
152.4	6.0	5 Ω ; 5 pF	-0.57 to 0.58 dB
127	5.0	6 Ω ; 6 pF	-0.74 to 0.75 dB
101.6	4.0	6 Ω ; 6 pF	-0.74 to 0.75 dB
76.2	3.0	7 Ω ; 7 pF	-0.88 to 0.89 dB

Figure 20-10. USB 2.0 USB Type-C Port with MUX and Redriver Topology

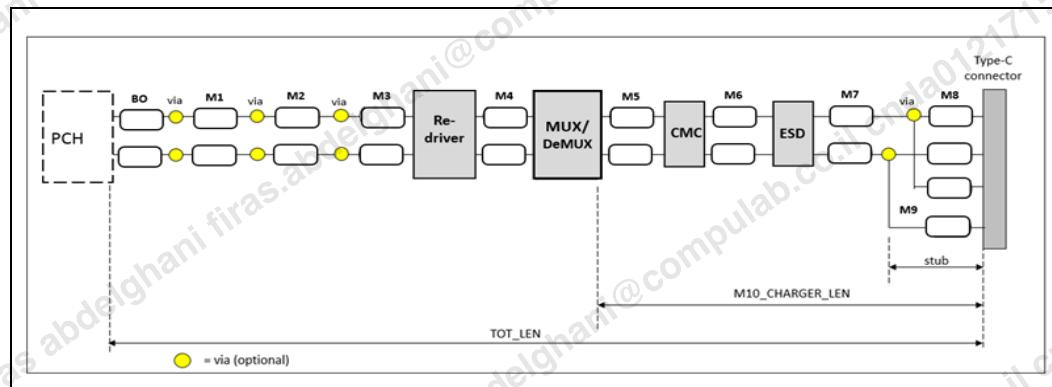


Table 20-3. USB 2.0 to USB Type-C Port Routing Guideline with MUX and Redriver Topology (Sheet 1 of 2)

Segment	Tline Type	Via Count	Length (mils)	Length (mm)
BO	MS/SL/DSL	1	598.42	15.2
M1+M2	MS/SL/DSL	1	NA	NA
M3 or M6	MS	1	149.6	3.8
M4	MS	0	1000	25.4
M7	MS	0	551.18	14
M8	MS	1	141.73	3.6
M9	SL/DSL		141.73	3.6
M5+M6+M7+M8 or M5+M6+M7+M9 (M10_charger_len)	MS	0	1000	25.4
Total Length			3000 (min) 13000 (max)	76.2 (min) 330.2 (max)

**Table 20-3. USB 2.0 to USB Type-C Port Routing Guideline with MUX and Redriver Topology (Sheet 2 of 2)**

Segment	Tline Type	Via Count	Length (mils)	Length (mm)
Notes:				
1. Length Matching allowed between P and N within a differential pair: a. Within same layer mismatch: $\pm 0.254\text{mm}$ ($\pm 10\text{mils}$). b. Total length mismatch: $\pm 0.381\text{mm}$ ($\pm 15\text{mils}$)				
2. Maximum number of vias allowed is 4 (including one implemented to accommodate stub).				
3. NA in the table implies that there is no strict trace length requirements for that particular segment.				
4. Reference plane recommended is continuous ground. Power plane referencing is also allowed.				
5. Maximum stub length allowed is 3.6mm (141.7 mils).				
6. Typical component (MUX) R/C: a. On-state resistance is 6 Ohm and capacitance is 6pF. b. Insertion Loss $<= -0.6\text{dB}$; Return Loss $<= -13\text{dB}$				
7. Redriver component: a. Placement of redriver component will be dependent on redriver pre- and post- channel equalization strength. It is recommended that the designer determine the optimum routing through the redriver datasheet and working with the component vendor.				

20.3.2 USB 3.1 Guidelines

This section describes the USB Type-C implementation details for USB 3.1 Gen1 and Gen2 speeds.

CC1/CC2 signal on the USB Type-C connector is used to detect the plug orientation and a decoding logic is used to decode the CC1/CC2 signal and control the high speed mux/switch to route USB 3.1 SS signals to the right differential pair.

CC1/CC2 has the options to be decoded with:

- Port chip capable of CC logic decoding
- Full Port controller with CC logic decoding (USB PD is optional on USB Type-C)

Any USB 3.1 port can support Dual Role (DRP) Mode on Coffee Lake, but only one at a time.

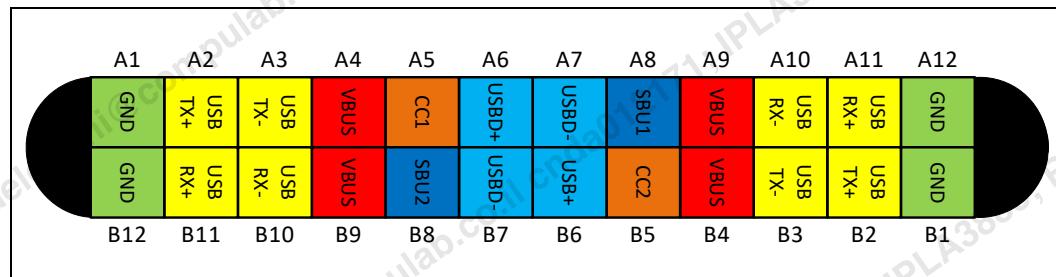
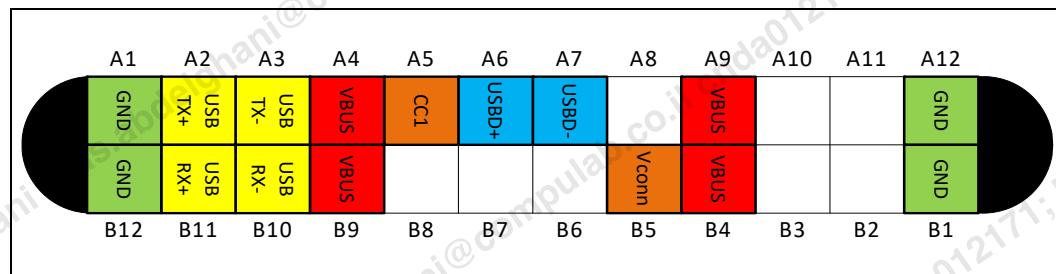
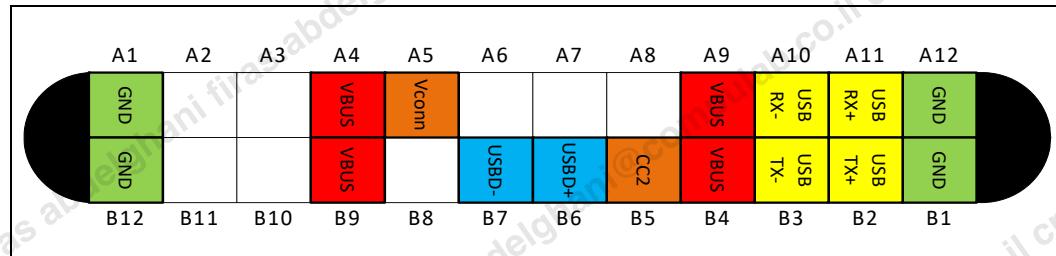
USB_ID and VBUS_SENSE signals are not needed for USB Type-C implementation with Type-C Port Controller (TCPC).

ESD protection devices is required for all signal connecting to PCH directly. For signals that are connected to 3rd party components like MUX/controller, refer to 3rd Party component specification to decide if platform level ESD device is needed.

CMC may be required to pass EMI test, therefore a CMC footprint is recommended.

This discrete implementation has high level of dependency on the discrete components used. Each discrete component might have slight different connectivity requirements. Refer to the discrete components datasheet and/or design guide to ensure the functionality of the design.

AC Cap might be needed on RX lines depending on the repeater part used. Suggest to follow recommendation from the repeater vendor.

Figure 20-11.USB Type-C Receptacle Pin Map - USB 3.1**Figure 20-12.USB Type-C Connector Connection (when the plug is 'Right Side Up')****Figure 20-13.USB Type-C Connector Connection (when the plug is 'Up Side Down')**

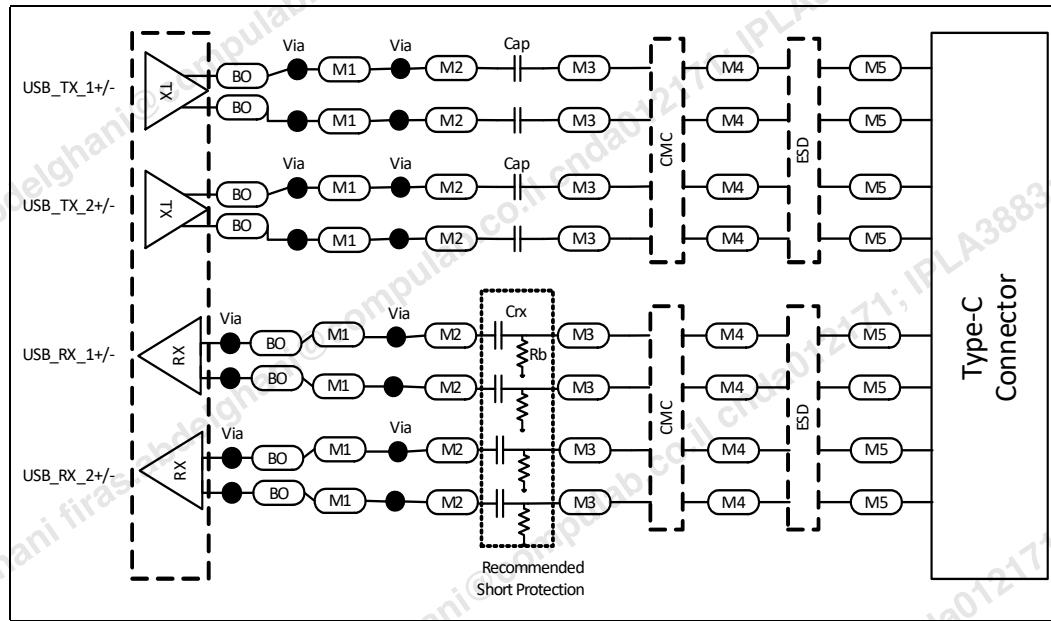
The presence of a mux/switch logic in this configuration will impact the signal quality of USB 3.1 SS signal. A repeater may be required to ensure the signal at USB Type-C connector still meet compliance requirement.

The following sub-sections describe the routing guidelines for following topologies

- USB 3.1 without active mux.
- USB 3.1 with active mux.

20.3.2.1 USB 3.1 without Active Mux

This section describes the design guidelines for USB 3.1 without active mux.

Figure 20-14. USB 3.1 Gen1/Gen2 External Topology Without Active Mux

Table 20-4. Routing Guidelines- USB 3.1 Gen2- External Topology Without Active Mux

Parameter	Segment	Stackup	Via Count	Gen2	
				Length (mm)	Length (mils)
Max Trace Length	BO	MS/SL/DSL	1	10.2	400
Max Trace Length	M1	MS/SL/DSL	1	96.5	3800
Max Trace Length	M2+M3+M4	MS	0	10.2	400
Max Trace Length	M5	MS	0	10.2	400
Total Max Trace Length				127.0	5000
Notes:					
1. Minimum PCB length is 50.8 mm (2000 mils).					
2. Reference is VSS for all segments.					
3. Crx Cap Value: 297nF to 363nF including tolerance.					
4. Rb Resistor Value: 220kΩ ±5%.					

Table 20-5. Routing Guidelines- USB 3.1 Gen1- External Topology Without Active Mux (Sheet 1 of 2) (Sheet 1 of 2)

Parameter	Segment	Stackup	Via Count	Gen1	
				Length (mm)	Length (mils)
Max Trace Length	BO	MS/SL/DSL	1	12.7	500
Max Trace Length	M1	MS/SL/DSL	1	104.1	4100
Max Trace Length	M2+M3+M4	MS	0	10.2	400
Max Trace Length	M5	MS	0	12.7	500
Total Max Trace Length				139.7	5500

Table 20-5. Routing Guidelines- USB 3.1 Gen1- External Topology Without Active Mux (Sheet 2 of 2) (Sheet 2 of 2)

Parameter	Segment	Stackup	Via Count	Gen1	
				Length (mm)	Length (mils)
Notes:					
1.	Minimum PCB length is 50.8 mm (2000 mils).				
2.	Reference is VSS for all segments.				
3.	Crx Cap Value: 297nF to 363nF including tolerance.				
4.	R _b Resistor Value: 220kΩ ±5%.				

Figure 20-15.USB 3.1 Gen1/Gen2 Internal Cable Topology Without Active Mux

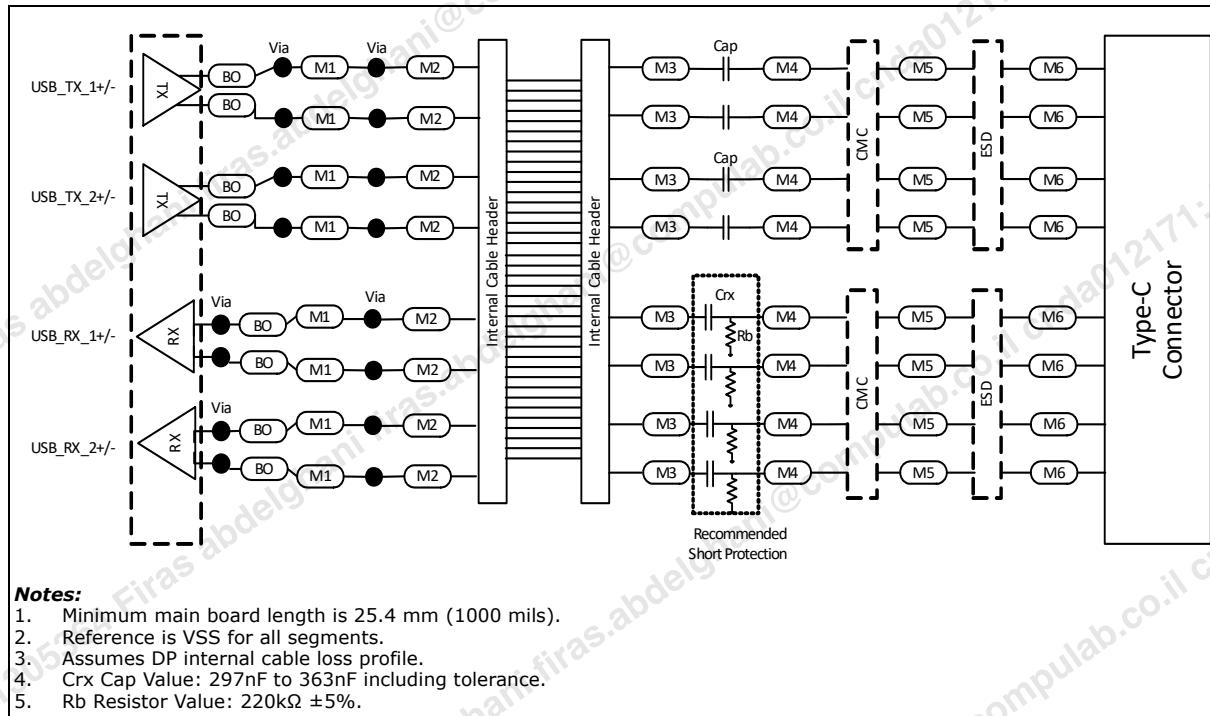


Table 20-6. Routing Guidelines- USB 3.1 Gen2- Internal Cable Topology Without Active Mux

Parameter	Segment	Stackup	Via Count	Gen2	
				Length (mm)	Length (mils)
Max Trace Length	BO	MS/SL/DSL	1	10.2	400
Max Trace Length	M1	MS/SL/DSL	1	48.3	1900
Max Trace Length	M2	MS	0	5.1	200
Max Trace Length	M3+M4+M5+M6	MS	0	12.5	500
Total Max Trace Length (BO+M1+M2)				63.5	2500
Total Max Trace Length (M3+M4+M5+M6)				12.5	500

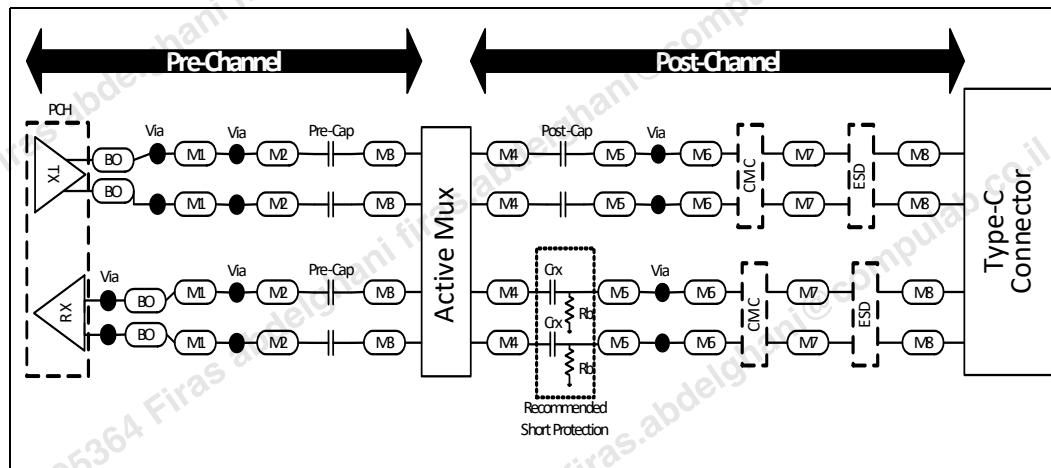
Table 20-7. Routing Guidelines- USB 3.1 Gen1- Internal Cable Topology Without Active Mux

Parameter	Segment	Stackup	Via Count	Gen1	
				Length (mm)	Length (mils)
Max Trace Length	BO	MS/SL/DSL	1	15.2	600
Max Trace Length	M1	MS/SL/DSL	1	68.6	2700
Max Trace Length	M2	MS	0	5.1	200
Max Trace Length	M3+M4+M5+M6	MS	0	50.8	2000
Total Max Trace Length (BO+M1+M2)				88.9	3500
Total Max Trace Length (M3+M4+M5+M6)				50.8	2000

20.3.2.1.1 USB 3.1 with Active Mux

This section describes the design guidelines for USB 3.1 with active mux. Active mux can be re-driver based or re-timer based. This following sections cover both these topologies.

Figure 20-16.USB 3.1 Gen1/Gen2 Active Mux External Topology



Notes:

- Minimum length: Pre-channel is 152.4 mm (6000 mils) and post-channel is 12.7 mm (500 mils).
- Reference for all segments is VSS.
- Crx Cap Value: 297nF to 363nF including tolerance.
- Rb Resistor Value: 220kΩ ±5%.



Table 20-8. Routing Guidelines- USB 3.1 Gen2 Active Mux External Topology (With Re-driver Based Active Mux)

Channel	Parameter	Segment	Stackup	Via Count	Gen2		
					Length (mm)	Length (mils)	
Pre-channel	Max Trace Length	BO	MS/SL/DSL	1	Note#1*	Note#1*	
	Max Trace Length	M1	MS/SL/DSL	1	Note#1*	Note#1*	
	Max Trace Length	M2+M3	MS	0	Note#1*	Note#1*	
Post-channel	Max Trace Length	M4 + M5	MS	1	7.6	300	
	Max Trace Length	M6+M7	MS		7.6	300	
	Max Trace Length	M8	MS		10.2	400	
Total Max Trace Length (Pre-channel)					Note#1*	Note#1*	
Total Max Trace Length(Post-channel)					25.4	1000	
Notes: Important Guidelines on Re-driver based Active Mux/Re-driver Topologies							
1. *Max pre-channel length at USB3.1 Gen 2 speeds (10Gb/s) depends on what the specific re-driver based active mux/re-driver selected can compensate for when used in conjunction with Intel PCH. Work with repeater vendor to ensure that the component being utilized will provide adequate signal integrity at the PCH. <ul style="list-style-type: none"> a. OEMs are recommended to use the CRB/RVP topologies as reference for pre-channel lengths which are achievable and validated by Intel. 2. In addition, it is recommended to refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with RDC#571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeater in customer system designs. 3. It is recommended that OEMs use re-driver based active mux/re-driver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines: <ul style="list-style-type: none"> a. During power on and receive detect phase, recommended transmitter common mode voltage (Vcm) and impedance values: <ul style="list-style-type: none"> • If (Vcm <= 1.2V), Repeater Impedance >= 1K ohm ELSE • (Vcm+Rx.detect pulse amplitude <= 2.2V) AND (Repeater Impedance >= 4.5K ohm). 							

Table 20-9. Routing Guidelines- USB 3.1 Gen1 Active Mux External Topology (With Re-driver Based Active Mux)

Channel	Parameter	Segment	Stackup	Via Count	Gen1		
					Length (mm)	Length (mils)	
Pre-channel	Max Trace Length	BO	MS/SL/DSL	1	12.7	500	
	Max Trace Length	M1	MS/SL/DSL	1	241.3	9400	
	Max Trace Length	M2+M3	MS	0	12.7	500	
Post-channel	Max Trace Length	M4 + M5	MS	1	7.6	300	
	Max Trace Length	M6+M7	MS		7.6	300	
	Max Trace Length	M8	MS		10.2	400	
Total Max Trace Length (Pre-channel)					266.7	10500	
Total Max Trace Length(Post-channel)					25.4	1000	
Notes: Important Guidelines on Re-driver based Active Mux/Re-driver Topologies							
1. Refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with RDC#571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeaters in customer system designs. 2. It is recommended that OEMs use re-driver based active mux/re-driver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines: <ul style="list-style-type: none"> a. During power on and receive detect phase, recommended transmitter common mode voltage (Vcm) and impedance values: <ul style="list-style-type: none"> • If (Vcm <= 1.2V), Repeater Impedance >= 1K ohm ELSE • (Vcm+Rx.detect pulse amplitude <= 2.2V) AND (Repeater Impedance >= 4.5K ohm). 							

**Table 20-10. Routing Guidelines- USB 3.1 Gen2 Active Mux External Topology (With Re-timer Based Active Mux)**

Channel	Parameter	Segment	Stackup	Via Count	Gen2		
					Length (mm)	Length (mils)	
Pre-channel	Max Trace Length	B0	MS/SL/DSL	1	10.2	400	
	Max Trace Length	M1	MS/SL/DSL	1	358.1	14100	
	Max Trace Length	M2+M3	MS	0	12.7	500	
Post-channel	Max Trace Length	M4 + M5	MS	1	101.6	4000	
	Max Trace Length	M6+M7	MS		15.2	600	
	Max Trace Length	M8	MS		10.2	400	
Total Max Trace Length (Pre-channel)					381.0	15000	
Total Max Trace Length(Post-channel)					127.0	5000	

Notes: Important Guidelines on Re-timer based Active Mux/Re-timer Topologies

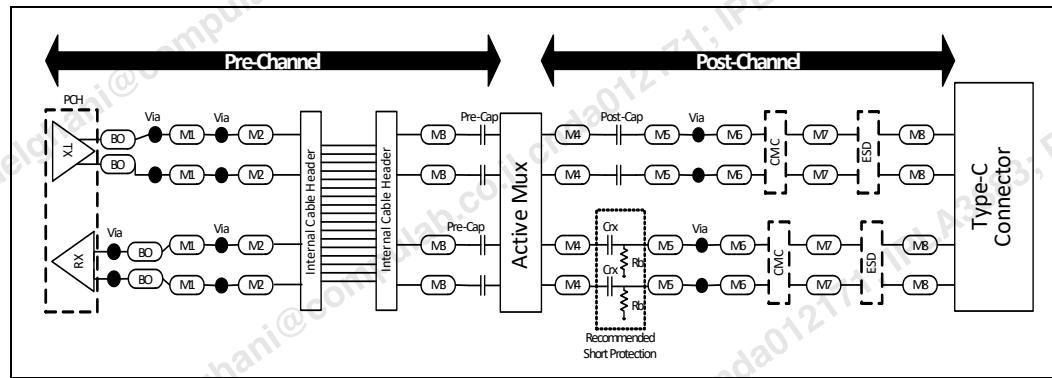
1. Refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with RDC#571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeaters in customer system designs.
2. It is recommended that OEMs use re-driver based active mux/re-driver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines:
 - a. During power on and receive detect phase, recommended transmitter common mode voltage (Vcm) and impedance values:
 - If (Vcm <= 1.2V), Repeater Impedance >= 1K ohm **ELSE**
 - (Vcm+Rx.detect pulse amplitude <= 2.2V) **AND** (Repeater Impedance >= 4.5K ohm).

Table 20-11. Routing Guidelines- USB 3.1 Gen1 Active Mux External Topology (With Re-timer Based Active Mux)

Channel	Parameter	Segment	Stackup	Via Count	Gen1		
					Length (mm)	Length (mils)	
Pre-channel	Max Trace Length	B0	MS/SL/DSL	1	12.7	500	
	Max Trace Length	M1	MS/SL/DSL	1	368.3	14500	
	Max Trace Length	M2+M3	MS	0	12.7	500	
Post-channel	Max Trace Length	M4 + M5	MS	1	53.3	2100	
	Max Trace Length	M6+M7	MS		53.3	2100	
	Max Trace Length	M8	MS		71.1	2800	
Total Max Trace Length (Pre-channel)					393.7	15500	
Total Max Trace Length(Post-channel)					177.8	7000	

Notes: Important Guidelines on Re-timer based Active Mux/Re-timer Topologies

1. Refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with CDI# 571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeaters in customer system designs.
2. It is recommended that OEMs use re-driver based active mux/re-driver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines:
 - a. During power on and receive detect phase, recommended transmitter common mode voltage (Vcm) and impedance values:
 - If (Vcm <= 1.2V), Repeater Impedance >= 1K ohm **ELSE**
 - (Vcm+Rx.detect pulse amplitude <= 2.2V) **AND** (Repeater Impedance >= 4.5K ohm).

**Figure 20-17.USB 3.1 Gen1/Gen2 Active Mux Internal Cable Topology****Notes:**

- Minimum length: Pre-channel is 50.8 mm (2000 mils) and post-channel is 12.7 mm (500 mils).
- Reference for all segments is VSS.
- Crx Cap Value: 297nF to 363nF including tolerance.
- Rb Resistor Value: 220kΩ ±5%.
- Assumes DP internal cable loss profile.

Table 20-12. Routing Guidelines- USB 3.1 Gen1/Gen2 Active Mux Internal Cable Topology (With Re-driver Based Active Mux)

Channel	Parameter	Segment	Stackup	Via Count	Gen1/Gen2	
					Length (mm)	Length (mils)
Pre-channel	Max Trace Length	BO	MS/SL/DSL	1	Note#1*	Note#1*
	Max Trace Length	M1	MS/SL/DSL	1	Note#1*	Note#1*
	Max Trace Length	M2	MS	0	Note#1*	Note#1*
	Max Trace Length	M3	MS	0	Note#1*	Note#1*
Post-channel	Max Trace Length	M4 + M5	MS	1	7.6	300
	Max Trace Length	M6+M7	MS	0	7.6	300
	Max Trace Length	M8	MS	0	10.2	400
Total Max Trace Length (Pre-channel)					Note#1*	Note#1*
Total Max Trace Length(Post-channel)					25.4*	1000*

Notes: Important Guidelines on Re-driver based Active Mux/Re-driver Topologies

1. *Max pre-channel length at USB3.1 Gen 2 speeds (10Gb/s) depends on what the specific re-driver based active mux/re-driver selected can compensate for when used in conjunction with Intel PCH. Work with repeater vendor to ensure that the component being utilized will provide adequate signal integrity at the PCH.
 - a. OEMs are recommended to use the CRB/RVP topologies as reference for pre-channel lengths which are achievable and validated by Intel.
2. In addition, it is recommended to refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with RDC#571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeater in customer system designs.
3. It is recommended that OEMs use re-driver based active mux/re-driver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines:
 - a. During power on and receive detect phase, recommended transmitter common mode voltage (Vcm) and impedance values:
 - If $(V_{cm} \leq 1.2V)$, Repeater Impedance $\geq 1K\text{ ohm}$ **ELSE**
 - $(V_{cm} + Rx.\text{detect pulse amplitude} \leq 2.2V)$ **AND** (Repeater Impedance $\geq 4.5K\text{ ohm}$).

**Table 20-13. Routing Guidelines- USB 3.1 Gen1/Gen2 Active Mux Internal Cable Topology (With Re-timer Based Active Mux)**

Channel	Parameter	Segment	Stackup	Via Count	Gen1/Gen2	
					Length (mm)	Length (mils)
Pre-channel	Max Trace Length	B0	MS/SL/DSL	1	7.6	300
	Max Trace Length	M1	MS/SL/DSL	1	205.7	8100
	Max Trace Length	M2	MS	0	5.1	200
	Max Trace Length	M3	MS	0	10.2	400
Post-channel	Max Trace Length	M4 + M5	MS	1	7.6	300
	Max Trace Length	M6+M7	MS	0	7.6	300
	Max Trace Length	M8	MS	0	10.2	400
Total Max Trace Length (Pre-channel)					228.6	9000
Total Max Trace Length(Post-channel)					25.4	1000

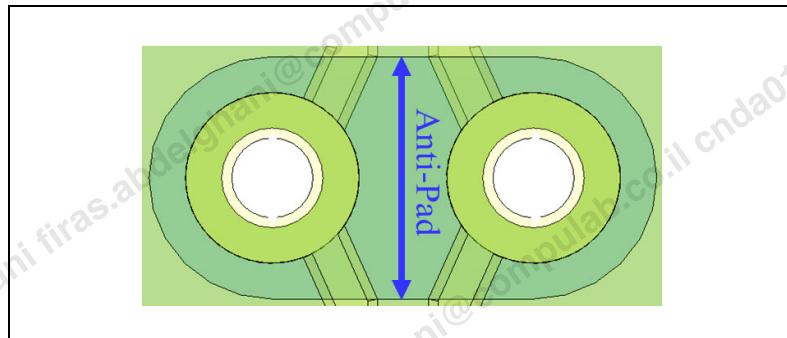
Notes: Important Guidelines on Re-timer based Active Mux/Re-timer Topologies

1. Refer to the white paper pertaining to the repeater integration (USB 3.1 Repeater Integration Technical White Paper Rev 0.9 with RDC#571574). The white paper illustrates in detail the fundamental differences between different repeater types (redriver vs retimer), and the efforts needed to enable such repeaters in customer system designs.
2. It is recommended that OEMs use re-driver based active mux/re-driver parts from 3rd party vendors which meet below requirements to avoid Electrical Over Stress (EOS) on USB3.1 receiver lines:
 - a. During power on and receive detect phase, recommended transmitter common mode voltage (Vcm) and impedance values:
 - If (Vcm <= 1.2V), Repeater Impedance >= 1K ohm **ELSE**
 - (Vcm+Rx.detect pulse amplitude <= 2.2V) **AND** (Repeater Impedance >= 4.5K ohm).

Note:**General Guidelines (applicable to all USB 3.1 USB Type-C topologies unless specified otherwise)**

- Length matching between P and N should be ± 10 mils within same layer and ± 15 mils for total length.
- Breakout Scheme: TX and RX breakout at different layers (non-interleaved scheme), for better crosstalk shielding performance. The main route supports interleaved routing and non-interleaved routing for maximum flexibility. However, breakout must be routed using a non-interleaved scheme.
- Microstrip Routing Support: Microstrip main route is also recommended albeit with shorter length than Stripline or Dual-Stripline.
- Breakout Length and Spacing: An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 - 6 mils) is allowed. But the total breakout length should still be within the length defined for each topology.
- Trace Geometry:
 - For Gen2, it is recommended to use 80-ohm trace geometry (with larger trace width), primarily to address routing insertion loss at 10Gbps.
 - For Gen1, it is recommended to use 85-ohm trace geometry (narrower trace width), for PCB real estate saving. It is worth noting that Gen2 with 80-ohm trace geometry is fully functional and backward compatible with Gen1 5Gbps signaling.
- Reference plane is recommended to be continuous ground.
- TX AC Capacitor Value: 220nF nominal (135-265nF range including tolerance).
- CMC Usage:
 - USB3 Only: Place TX CMCs; RX CMCs are optional
 - USB3 and DP: Place both TX and RX CMCs due to emission from DP.
- Recommended Short Protection Circuit (Optional): It is recommended to include the RC circuit (using the Crx and Rb values provided) to comply with USB ECN "RX AC Coupling Capacitor Option" to provide ESD/EOS protection, and set RX bias at the Type-C connector.
 - The current PDG topologies are designed to optimize for ESD protection. For applications where VBUS = 5V, these topologies can address EOS also by using a TVS device on the board, having a breakdown voltage higher than 5V.
 - The USB 3.1 USB-IF ECN "Rx AC Coupling Capacitor Option" implementation to address possible EOS is currently under evaluation. Refer to USB3.1 Type-C USB-IF ECN Update (IBL#575549) for details.
- CMC Bypass: A single 0 Ω resistor per signal trace should be available to be used to bypass the CMC content if it is proven that there is no EMI risk on USB3.1 TX/RX signals. However, the 0 Ω resistor must be placed near the connector at the same recommended location as the CMC.
- ESD may/may not be required depending on the 3rd party's device. On the removal of discrete ESD, there are two requirements that have to be met:

- Mux/ Redriver can handle the ESD at least 8kV
- Mux/ Redriver to be placed near to USB-C connector (< 1")
- USB Type-C Possible Configurations:
 - No dual role (related to cable orientation) where two independent USB3.0 signal are connected to the USB-C connector.
 - Dual role whereby a mux/redriver switch are presented to support right side up/ up side down plug orientation of the USB-C connector.
 - Dual role with Alternate Mode (DP IO).
- Refer to specific active mux vendor for detailed platform design guide and active mux settings.
- For USB3.1Gen2, the via stub length < 15mils.
- Via Anti-pad: Oval anti-pad size of 40mils is required for better impedance matching (see figure below).

Figure 20-18.Oval Anti-pad

20.3.3 USB Type-C with DP* as Alternate Mode

USB Type-C connector support DP Alternate Mode where you can have:

- Concurrent USB 3.1 (Gen1 or Gen2) data stream with DP x 2 display stream
- Concurrent USB 2.0 (LS/FS/HS) data stream with DP x 4 display stream utilizing all the differential pairs on the connectors

In DP Alternate Mode SBU1/SBU2 will be connected to DP AUX+/DP AUX- signal to support DP functionality. DP HPD signal will leverage CC communication as hot plug detect. HPD is from EC which is connected to CC lines through port controller.

ESD protection devices is required for all signal connecting to Coffee Lake directly. For signals that are connected to 3rd party component like MUX/controller, refer to 3rd Party component specification to decide if platform level ESD device is needed.

CMC may be required to pass EMI test therefore a CMC footprint is recommended.

Figure 20-19.USB 3.1 and DP x 2 USB Type-C Connector Mapping (Right Side Up)

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12	
GND	TX+	USB	TX-	USB	VBUS	CC1	USBD+	USBD-	DP	AUX+	VBUS	GND
GND	RX+	USB	RX-	USB	VBUS	AUX-	DP	USB-	USB+	CC2	VBUS	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	

Figure 20-20.USB 3.1 and DP x 2 USB Type-C Connector Mapping (Up Side Down)

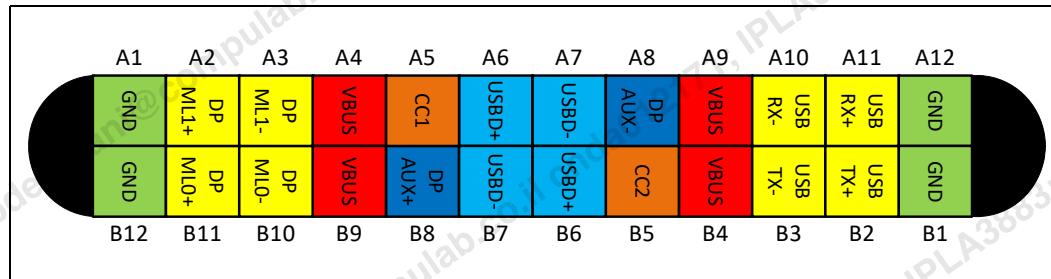
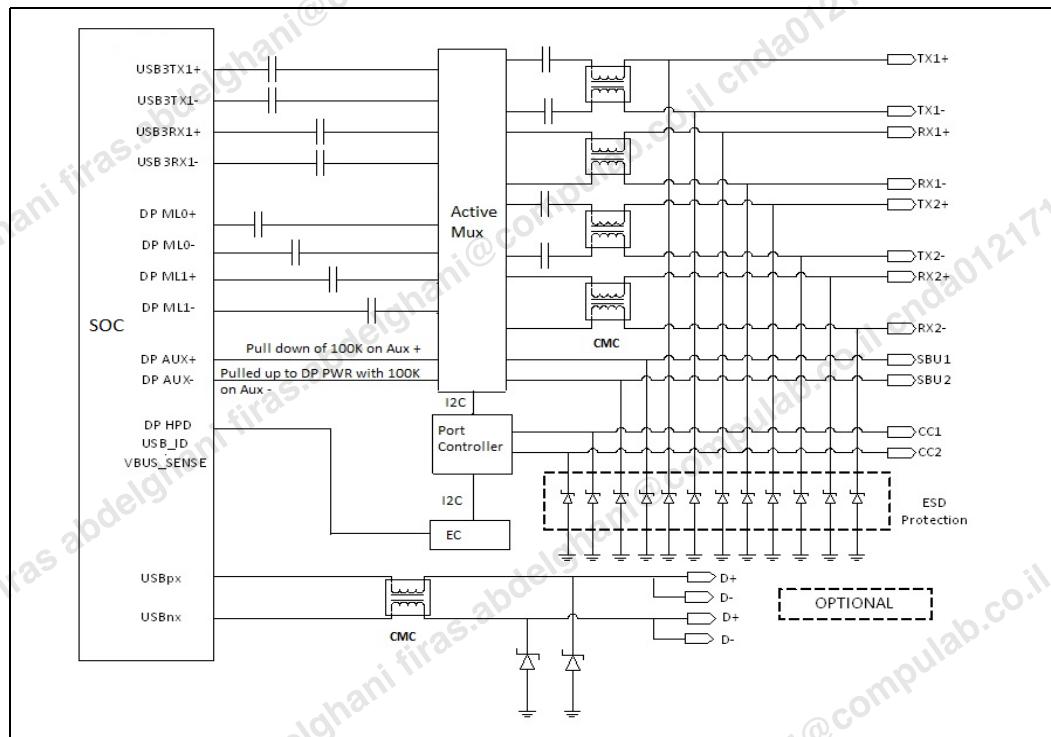


Figure 20-21.USB 3.1 and DP x 2



Note:

The figure above is a high level example implementation block. The actual implementation on schematic may vary.

AC Cap might be needed on RX lines depending on Redriver/Repeater. Suggest to follow recommendation from Redriver.



Figure 20-22.USB and DP x 4 USB Type-C Connector Mapping (Right Side Up)

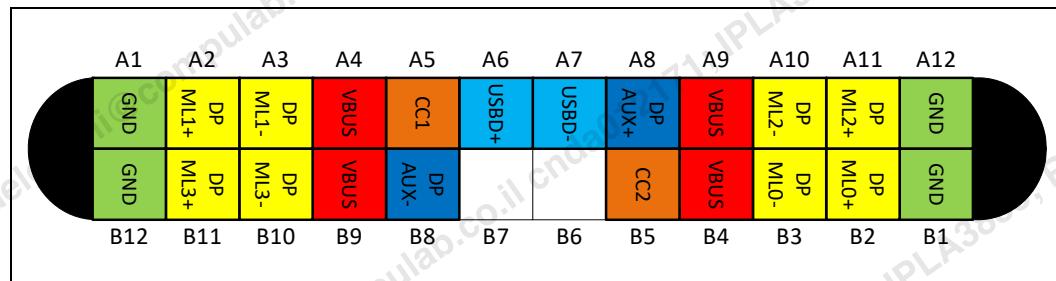


Figure 20-23.USB and DP x 4 USB Type-C Connector Mapping (Up Side Down)

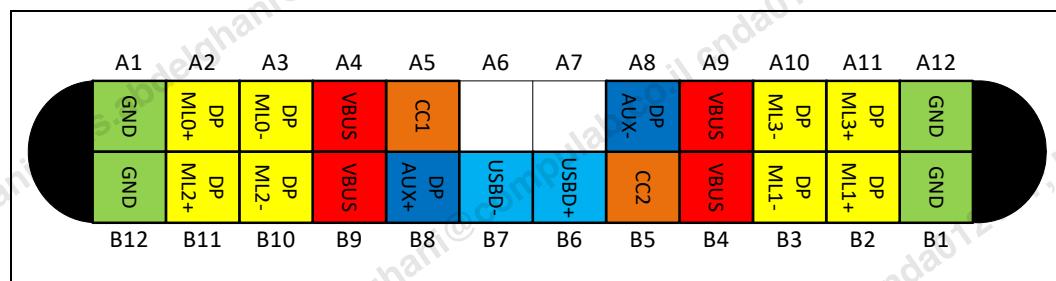
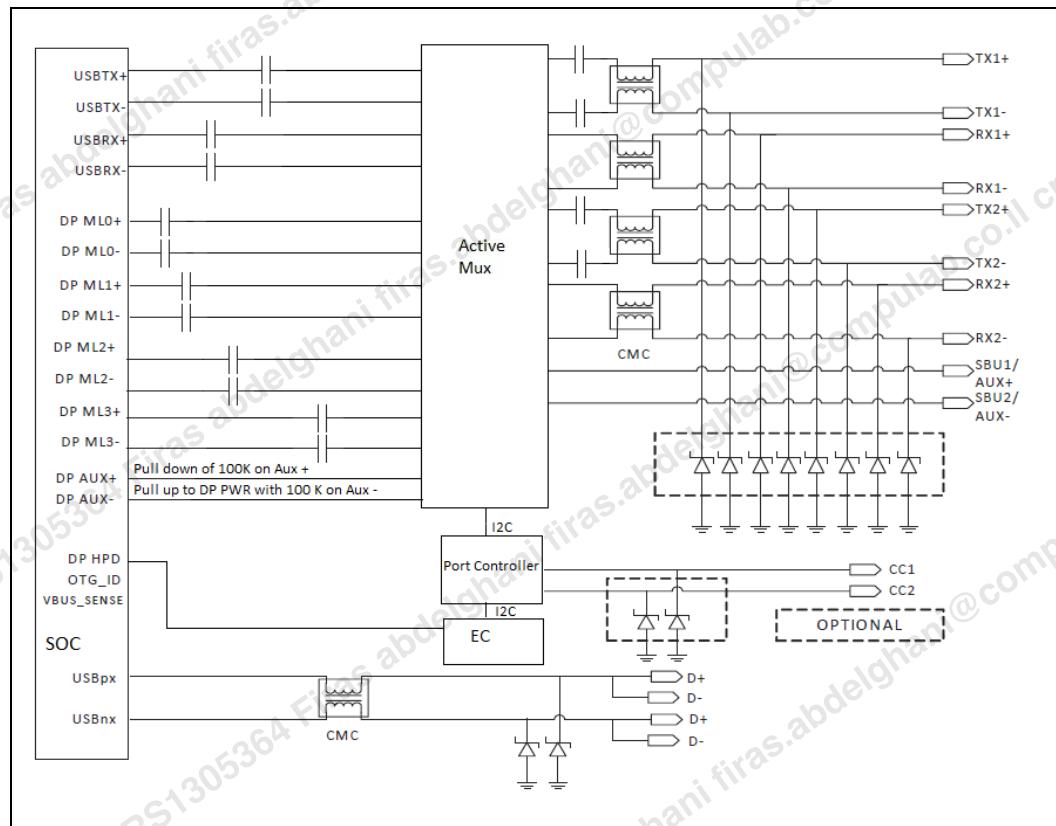


Figure 20-24.USB 3.1 and DP x 4 Discrete Solution



Note:

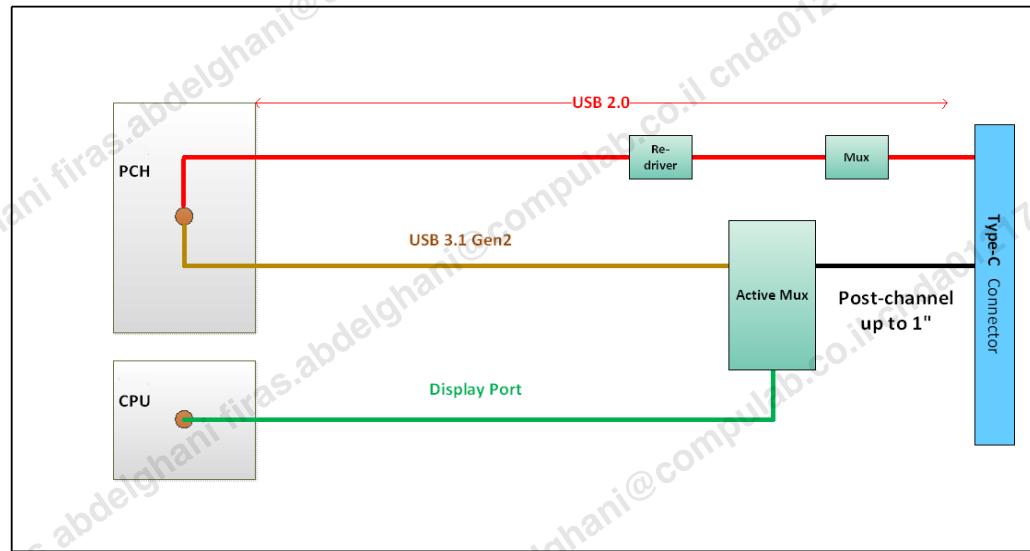
The figure above is a high level example implementation block actual implementation on schematic may vary.

AC Cap might be needed on RX lines depending on Redriver/Repeater. Suggest to follow recommendation from Redriver vendor.

An active mux should be used. Intel(R) DCI OOB over passive mux will not be supported.

Post-channel length (total length after active mux) is restricted to 1" (see figure below)

Figure 20-25.System Design Example with USB Type-C Supporting DP as Alternate Mode


Notes:

1. USB 2.0 PCB length up to 13" (pre- and post-channels)
2. USB 3.1 Gen2 PCB length up to 10" (pre-channel)
3. DisplayPort PCB length up to 8" (pre-channel)

Figure 20-26.DP over USB-C- External Topology

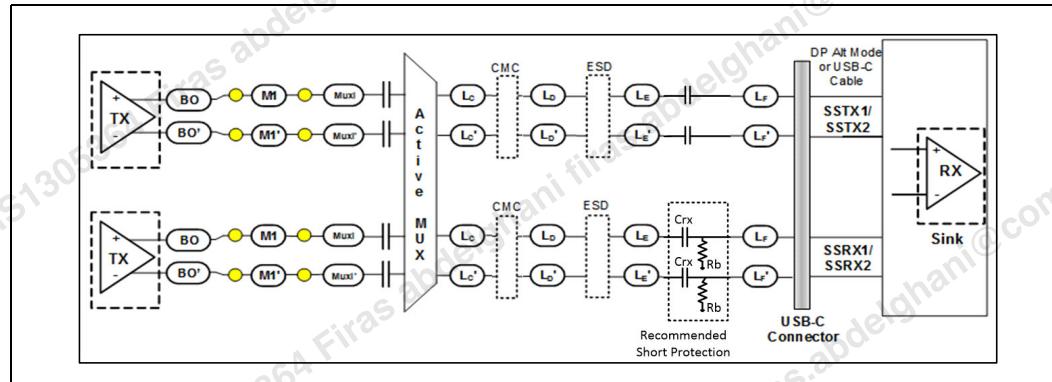
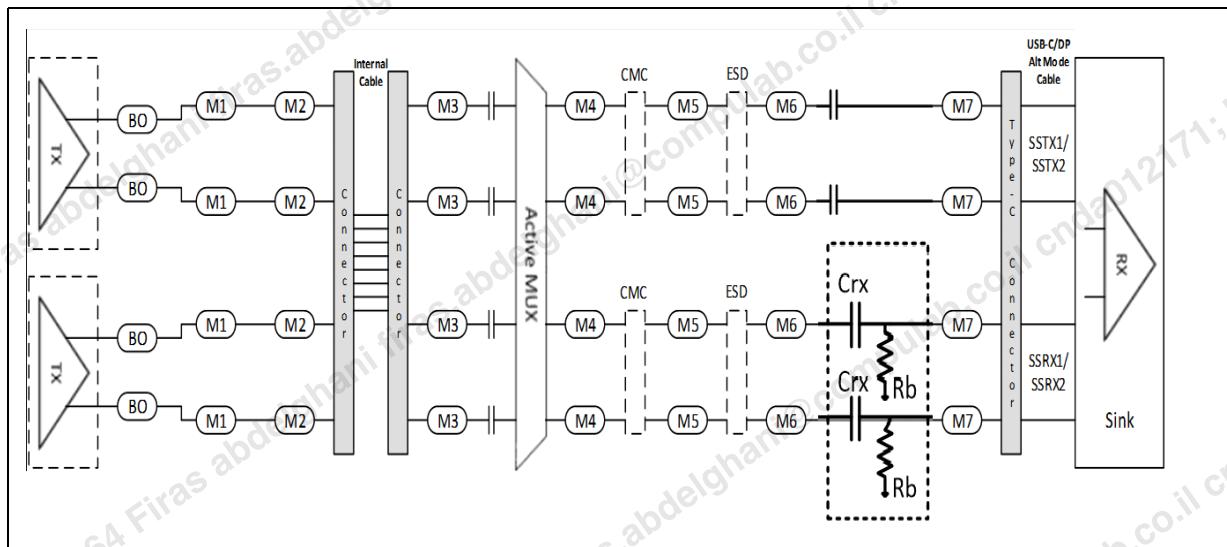


Table 20-14. Routing Guidelines- DP over USB-C External- B Topology

Parameter	Segment	Stackup	Length (mm)	Length (mils)
Trace length maximum	B0	MS/SL/DSL	12.7	500
Trace length maximum	M1	MS/SL/DSL	190.5	7500
Trace length maximum	MuxL	MS	190.5	7500
Trace length maximum	LC to LF	MS	50.8	2000
Total trace length maximum	Total	MS	228.6	9000
Maximum number of vias				2
Notes:				
1. Crx capacitor value 297nF to 363nF, 25v. 2. Rb resistor value 220 kOhm ±5%.				

Figure 20-27.DP over USB-C Internal Cable Topology**Table 20-15. Routing Guidelines- DP over USB-C- Internal Cable Topology**

Parameter	Segment	Stackup	Length (mm)	Length (mils)
Trace length maximum	B0	MS/SL	12.7	500
Trace length maximum	M1+M2	MS/SL/DSL	177.8	7000
Trace length maximum	M3	MS/SL/DSL	25.4	1000
Trace length maximum	M4+M5+M6+M7	MS/SL/DSL	25.4	1000
Total trace length maximum	Total	MS	241.3	9500
Maximum vias allowed				3
Notes:				
<ul style="list-style-type: none"> Active Mux Assumption: With embedded mux/switch. Design guidelines may differ across multiple 3rd party devices. Refer to specific 3rd party vendor for details on platform design guideline and the corresponding device's setting. AC Capacitor Values: nominal 100 nF recommended (tolerance 75 nF to 265 nF) Reference Plane: Continuous Ground Only Internal Cable Insertion Loss Assumption: 1.2dB at 2.5GHz, 3.3dB at 5GHz Crx capacitor value 297nF to 363nF, 25v. Rb resistor value 220 kOhm ±5%. 				

Figure 20-28.DP AUX over USB-C- External Topology

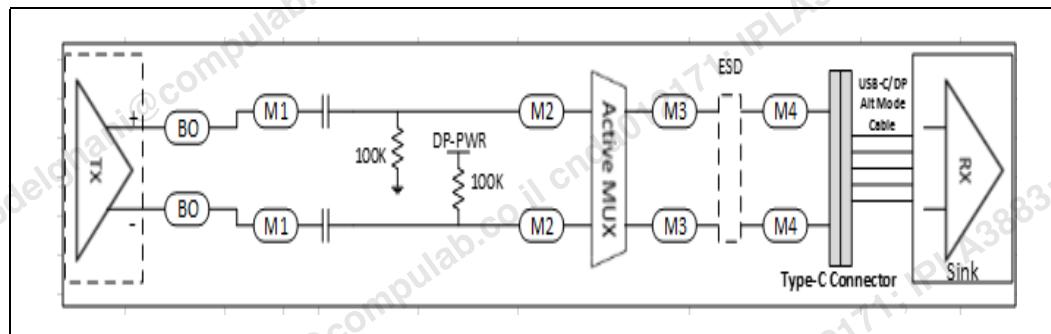


Table 20-16. Routing Guidelines- DP AUX over USB-C- External Topology

Parameter	Segment	Stackup	Length (mm)	Length (mils)
Trace length maximum	B0	MS/SL	20.3	800
Trace length maximum	M1+M2	MS/SL/DSL	330	13000
Trace length maximum	M3+M4	MS/SL/DSL	25	984
Total trace length maximum	Total	MS	330	13000

Figure 20-29.DP AUX over USB-C- Internal Cable Topology

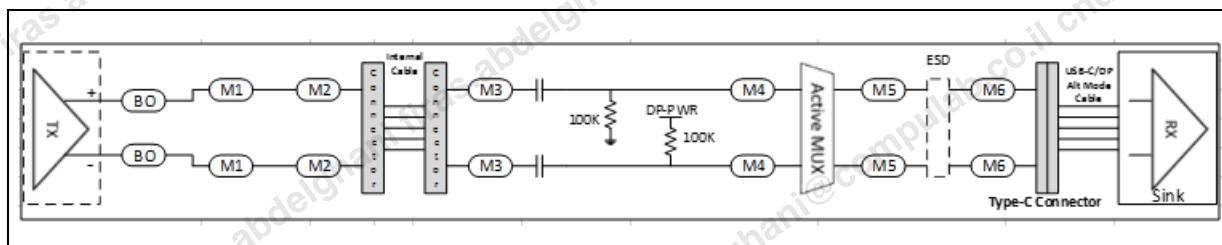


Table 20-17. Routing Guidelines- DP AUX over USB-C- Internal Cable Topology

Parameter	Segment	Stackup	Length (mm)	Length (mils)
Trace length maximum	B0	MS/SL	20.3	800
Trace length maximum	M1+M2+M3+M4	MS/SL/DSL	330	13000
Trace length maximum	M5+M6	MS/SL/DSL	25	984
Trace length maximum	Mcable		178	7007
Total trace length maximum	Total	MS	330	13000

20.4 USB Type-C Power Delivery

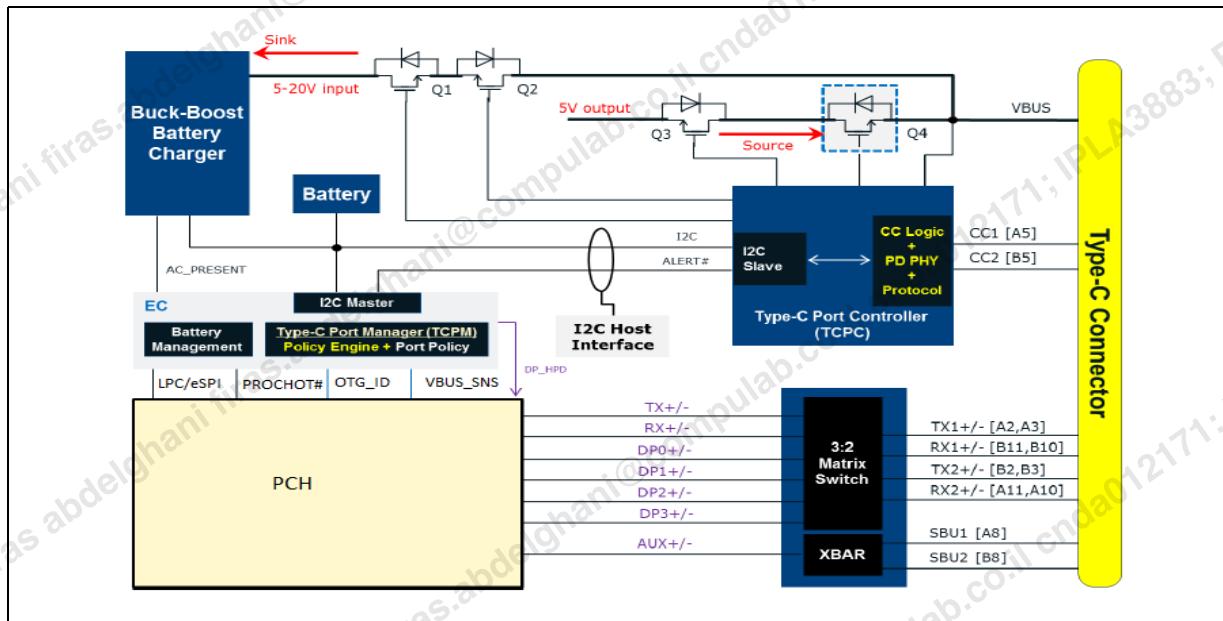
20.4.1 USB Type-C VBUS and VCONN Control

Since USB PD may be supported on a USB Type-C connector, VBUS on the connector could be 5V, 9V, 15V or 20V. It is critical not to share VBUS with any other USB connectors as the operating VBUS may be different.

A Buck boost charger will be needed to support charging (Consumer mode) with different voltages (5V to 20V). By default VBUS on a USB Type-C connector shall be off before a DFP or UFP is connected and established. Therefore additional logic will be

needed to control VBUS on a USB Type-C connector to switch on only when needed. As for VCONN, once a valid devices/cable is plugged in the unconnected CC pin will be reconfigured to VCONN.

Figure 20-30.USB-C PD System Block Diagram for Clamshell Design



Note:

This sample block diagram is for a USB configuration capable of providing up-to 5V@3A VBUS. This also uses buck-boost charger to allow sink 5-20V through VBUS. Actual implementation might vary.

20.4.2 USB Type-C VBUS Options

USB Type-C connector supports multiple power options as below:

- Default USB Power
- 1.5A @ 5V
- 3.0A @ 5V
- USB PD

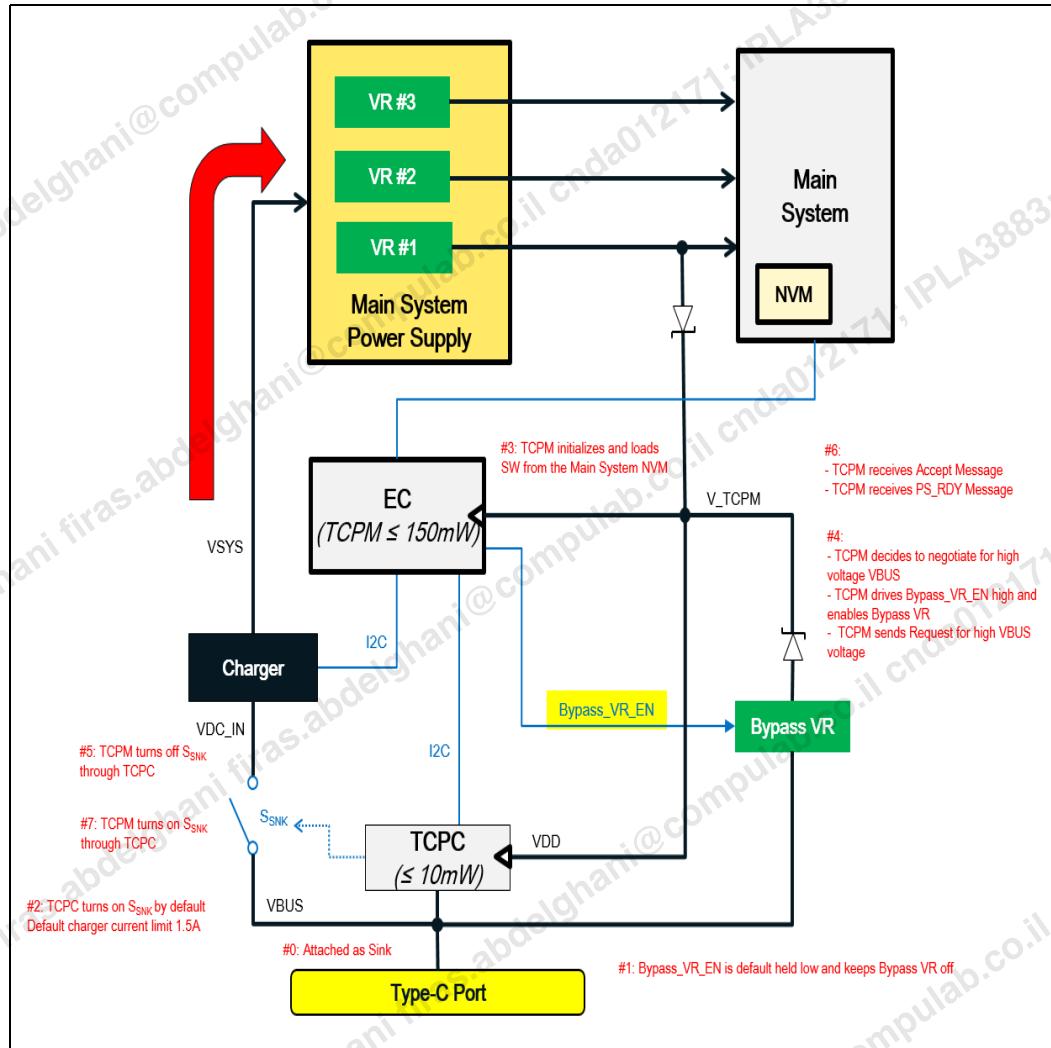
For Default USB Power, USB Type Power Delivery of 1.5A @5 V and 3.0A @5V, a DFP need to advertise the supported power options through pull up on the CC pins.

For USB PD, the power capability is advertised through the USB-C Port/PD Controller.

20.4.2.1 PTBB- PD Design Considerations

The PTBB (Powered Through Buck-Boost) charger block diagram is given below:

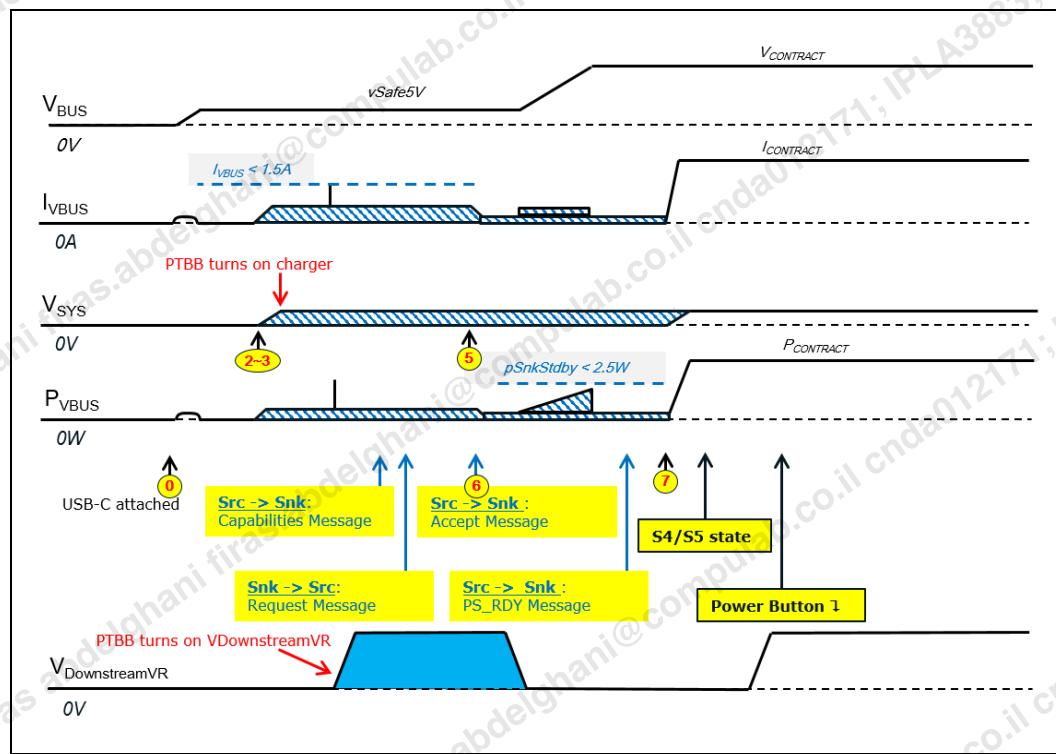
In this architecture, the TCPm shares the flash memory with the main system. The typical boot sequence is given below:



#6: EC receives Accept Msg and PS_RDY.

#7: EC may turn on Sink Path based on the negotiation

The power sequence timing diagram (G3 --> S4/S5) is shown below:



Legend:

1. VSYS: Output voltage from NVDC charger.
2. VDownstreamVR: Platform Power Rails (3.3V, 5V etc)

Notes:

1. While designing downstream VRs, please ensure the downstream VR's inrush power and loading is always lower than 6W. This is to prevent system from not being able to boot with USB-C charger during dead battery condition.
2. Tips to reduce inrush current
 - a. Increase downstream VR ramp-up time
 - b. Reduce downstream VR output capacitance.
 - c. Add load switches to turn off unused downstream VRs.

20.5

Overcurrent Protection

Refer to USB 2.0 for OC protection circuit guidelines, and PCH EDS for pin mapping details.

20.6 Layout Optimization

20.6.1 CC Pins Layout

CC signals on USB Type-C is both a signal and a power depends on its connection, as the unconnected CC signal will become Vconn which is a power supply that can supply up to 0.3A @ 5V. It is recommended to have at least 10 mils trace width to reduce trace DC resistance and ensure a smooth power delivery when acting as Vconn. DC resistance need to be kept low so that Vconn does not fall below 4.75V which is the minimum voltage allow under USB Type-C specification. With 10 mils trace width, it is possible to route up-to 10 inch on a 1 oz copper layer while keeping the voltage >4.75V. On 1/2 oz copper layer, trace width will need to be >15 mils to achieve same result.

Table 20-18. CC Signals Routing Guide

Trace Width	Copper thickness	Max Length
0.254 mm	1oz	254 mm
0.381 mm	1/2 oz	254 mm

20.7 Type-C Connector Footprint Voiding Guideline

In order to minimize the impedance discontinuity at the connector connection to board, it is recommended to cut void at the connecting pins. Refer to figure below for sample of ground void in PTH or SMT pins.

Figure 20-31.USB Type-C PTH Ground Void

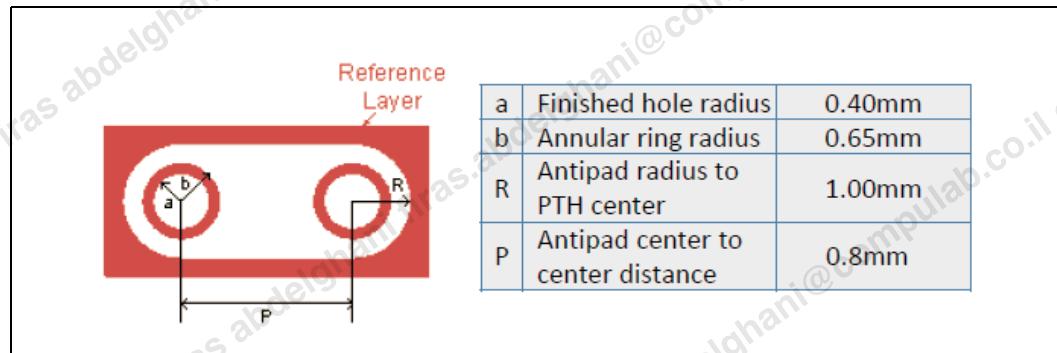
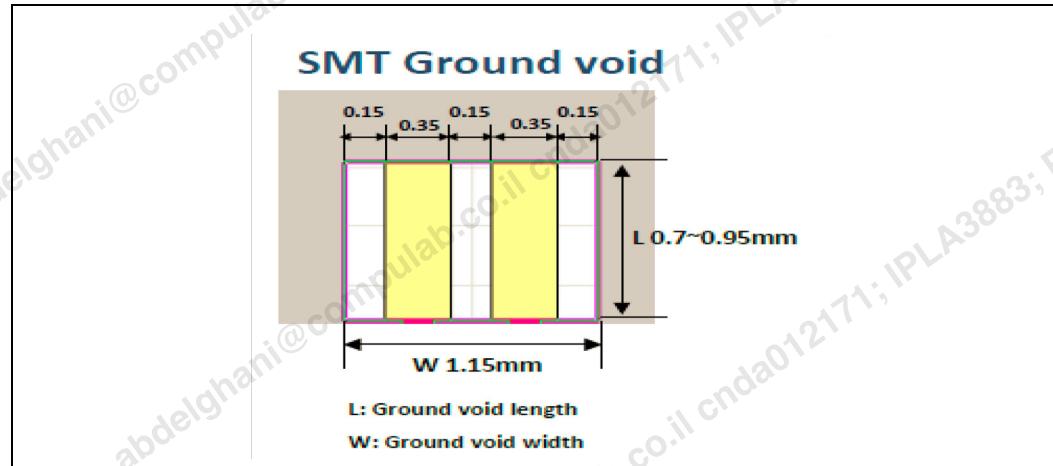




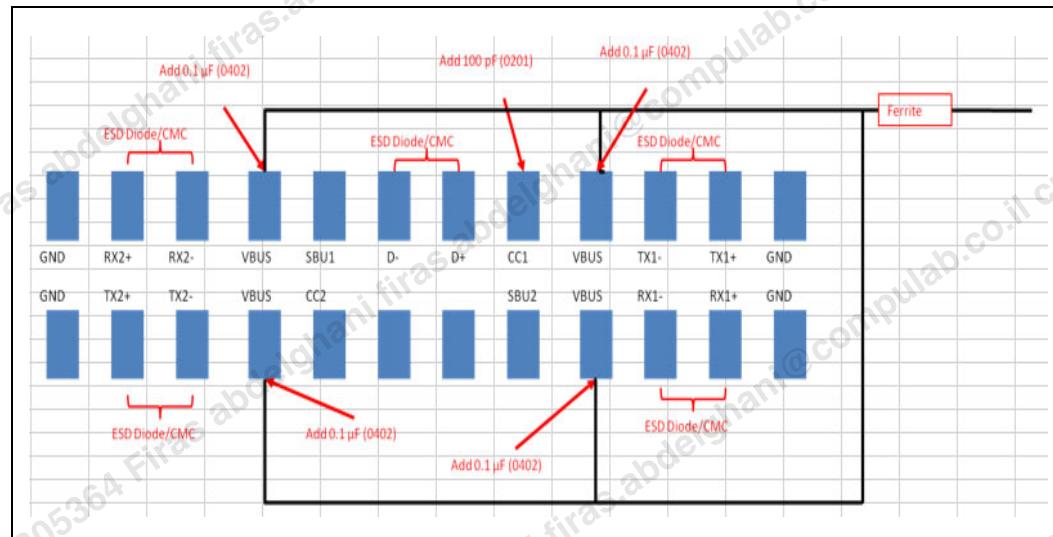
Figure 20-32.USB Type-C SMT Pins Ground Void



20.8 USB Type-C Component Selection Guidelines

Refer to PCL for Intel recommended parts. The below figure shows the USB Type-C component considerations for the connector.

Figure 20-33.USB Type-C Component Considerations



20.9 Reference Documents

USB 3.1 Type-C USB-IF ECN Update: 575549

High Speed Internal Connector and Cable Specification (Intel Technical White-paper): [549136](#)

Intel Channel Checker (ICC) for Client Re-driver CQC Analysis (Intel Software for Redriver Topology Analysis): [556174](#)



USB Type-C

USB 3.1 Specification (Industrial Specification): www.usb.org

USB 3.1 Internal Cable and Connector Implementation (Industrial Specification):
www.usb.org

Compliance (Industrial Specification): www.usb.org

§ §



21 PCH Signal Glitch Free Implementation Requirements

21.1 Overview

Certain PCH signals require special board implementation to ensure glitch free operation during boot process. Failure to meet the requirements may cause the signals to glitch during power sequencing and negatively impact the PCH behavior as well as external devices.

21.2 Implementation Details

Table 21-1, Table 21-2, and Table 21-3 below summarize the requirements.

Different options (implementing pull-down resistors or capacitors) are provided to meet the requirements. The options are intended for board implementation flexibility. For some signals, a cap or resistor site is recommended for board prototype designs and the site can be removed later on if not needed.

For the cap implementation option, the cap value depends on the 3.3V ramp rate of the VR on the motherboard, regardless of the signals being in 3.3V or 1.8V signaling mode.

For the pull-down resistor option, the resistor value depends on the signaling mode of the signal (3.3V or 1.8V).

Table 21-1. Signals Required Cap or Pull-Down Resistor

Signal Name	Option 1 (Cap Implementation)		Option 2 (Pull-down Resistor Implementation)		Note
	3.3V Ramp Rate from 5-50ms	3.3V Ramp Rate Less than 5ms	3.3V Signaling Mode	1.8V Signaling Mode	
GPD4 / SLP_S3# GPD5 / SLP_S4# GPD6 / SLP_A# GPD9 / SLP_WLAN# SLP_SUS# SLP_LAN#	330 nF	33 nF	100 K	75K	Cap or pull-down resistor is required
SPI0_CLK	N/A	N/A	100K	75K	Pull-down resistor is required.

**Table 21-2. Signals Recommended with Cap or Pull-down Resistor Sites**

Signal Name	Option 1 (Cap Implementation)	Option 2 (Pull-down Resistor Implementation)	Note
GPD10 / SLP_S5# GPP_A14 / SUS_STAT# / ESPI_RESET	Cap site	Pull-down resistor site	Site for cap or pull-down resistor only.
GPP_B13 / PLTRST# HDA_BCLK / I2S0_SCLK HDA_RST# / I2S1_SCLK I2S1_SFRM / SNDW2_CLK	N/A	Pull-down resistor site	Site for pull-down resistor only.

Table 21-3. Signals Required Pull-up Resistor

Signal Name	Pull-Up Resistor Value	Note
GPP_A7 / PIRQA# / ESPI_ALERT0#	An external Pull-up 8.2 KΩ ~10 KΩ to V3.3S power rail is required.	Pull-up resistor is required.
GPP_B12/SLP_S0#	3.3V Signaling Mode - 100K 1.8V Signaling Mode - 75K	Pull-up resistor is required if a device is monitoring SLP_S0# before RSMRST# de-assertion

§ §



22 MIPI SoundWire* Interface Design Guidelines

For Coffee Lake platform, the SoundWire interface is a new emerging interface targeting (but not limited to) the phone, mobile, and desktop market as an alternative to Slimbus. Its main advantage is the connection simplicity with a 2 wire multi-drop topology + PDM streaming capabilities. For the Cannon Lake PCH there are 4 separate SoundWire* interfaces that can be used.

22.1 SoundWire Platform Specific Important Information

On Coffee Lake platform the SoundWire interface pins are partially multiplexed with legacy DMIC, I2S, and HD-A audio interfaces. The SoundWire interface and other audio can be configured as either (and in some cases simultaneously) for connection to end devices. See the Cannon Lake PCH EDS for specific sku pins assignments and multiplexing details.

22.2 SoundWire Signal Description

Table 22-1. SoundWire Signals

Signal Name	Description
SNDW1_DATA	SoundWire Data 1: Serialized data line containing frame and data being transmitted /Received
SNDW1_CLK	SoundWire Clock 1: Serial bit clock used to control the timing of a transfer.
SNDW2_DATA	SoundWire Data 2: Serialized data line containing frame and data being transmitted /Received
SNDW2_CLK	SoundWire Clock 2: Serial bit clock used to control the timing of a transfer.
SNDW3_DATA	SoundWire Data 3: Serialized data line containing frame and data being transmitted /Received
SNDW3_CLK	SoundWire Clock 3: Serial bit clock used to control the timing of a transfer.
SNDW4_DATA	SoundWire Data 4: Serialized data line containing frame and data being transmitted /Received
SNDW4_CLK	SoundWire Clock 4: Serial bit clock used to control the timing of a transfer.

22.3 SoundWire Topology Guidelines

There are several topologies supported in Coffee Lake for SoundWire:

- Large System Topology - Single Load Configuration Using Cables.
- Large System Topology - Single Load Configuration with Device Down.

The following subsections outlines the routing requirements for each topology

22.3.1 Large System Topology - Single Load Configuration Using Cables

Figure 22-1. SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Cabled Load Configuration Diagram

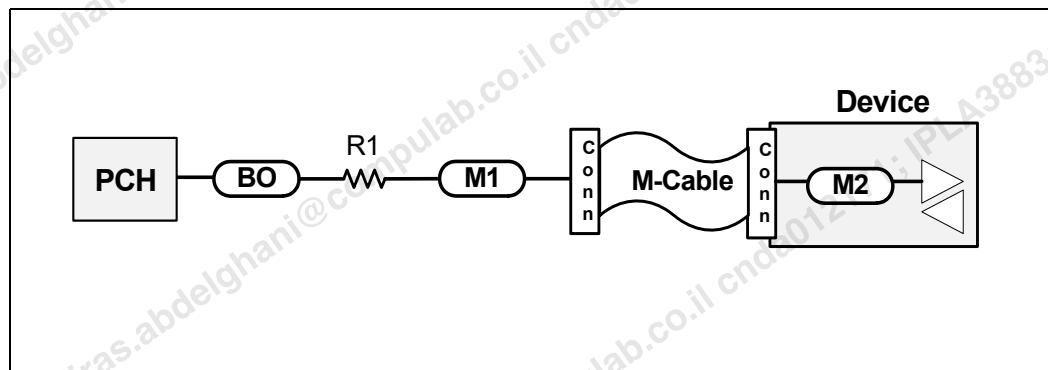


Table 22-2. SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Cabled Load Routing Guidelines

Parameter ¹	Segment	Stack-up	Units	Recommendation
Maximum Trace Length	BO	MS/SL/DSL	mils	500
Maximum Trace Length	M1	MS/SL/DSL	mils	7480.31
Maximum Trace Length	M2	MS/SL/DSL	mils	5905.51
Cable Length Maximum	M-Cable ³	NA	mils	13779.53
Overall Length Maximum	B0+M1+M-Cable+M2	MS/SL/DSL	mils	27665.35
Resistor Minimum Distance from PCH	R1	MS/SL/DSL	mils	500
Trace Length Mismatch Maximum between Clock and Data	NA	NA	mils	200
Resistor Value	R1	NA	Ω	22
Max Vias Single Load	NA	NA	count	4
Maximum Operating Frequency Single Load	NA	NA	MHz	6
Port# supported in this configuration	NA	NA	#	1, 2, 3, and 4
End Device Buffer Impedance Target	NA	NA	Ω	90
PCH Buffer	NA	NA	Type	HDA and GPPD
PCH Buffer Impedance Target ²	NA	NA	Ω	50

1. Routes should be referenced to GND for entire route.
2. The buffer impedance target should be 50ohm, slew 00. Refer to the EDS/BIOS programming guide for more details.
3. Cable characteristic impedance target to $50 \Omega \pm 5\%$. Simulation analysis covers characteristic impedance of 45-60 Ω including cable manufacturing tolerance.

22.3.2 Large System Topology - Single Load Configuration with Device Down

Figure 22-2. SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Load Device Down Configuration Diagram

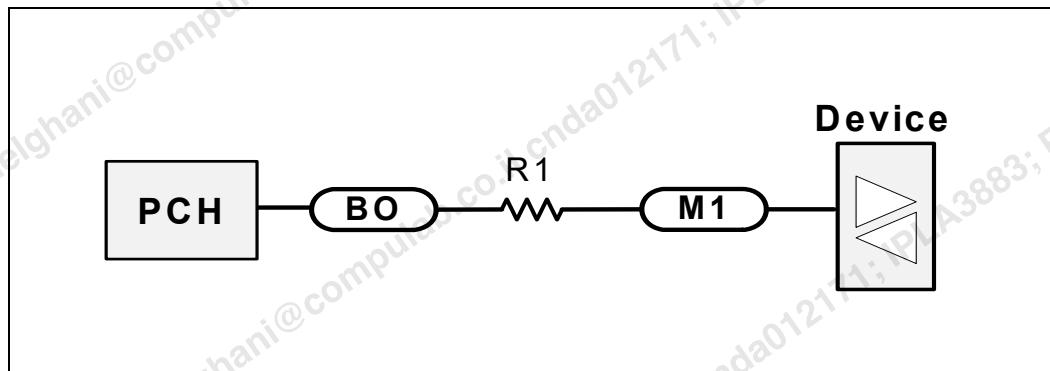


Table 22-3. SNDW1_DATA to SNDW4_DATA/ SNDW1_CLK to SNDW4_CLK Single Load Down Device Routing Guidelines

Parameter ¹	Segment	Stack-up	Units	Recommendation
Maximum Trace Length	BO	MS/SL/DSL	mils	500
Maximum Trace Length	M1	MS/SL/DSL	mils	18897.60
Overall Length Maximum	B0+M1	MS/SL/DSL	mils	19397.60
Resistor Minimum Distance from PCH	R1	MS/SL/DSL	mils	500
Trace Length Mismatch Maximum between Clock and Data	NA	NA	mils	200
Resistor Value	R1	NA	Ω	22
Max Vias Single Load	NA	NA	count	4
Maximum Operating Frequency Single Load	NA	NA	MHz	6
Port# supported in this configuration	NA	NA	#	1, 2, 3, and 4
End Device Buffer Impedance Target	NA	NA	Ω	90
PCH Buffer	NA	NA	Type	HDA and GPPD
PCH Buffer Impedance Target ²	NA	NA	Ω	50

1. Routes should be referenced to GND for entire route.
2. The buffer impedance target should be 50ohm, slew 00. Refer to the EDS/BIOS programming guide for more details.

22.4 Additional Guidelines

22.4.1 Adjusting Drive Impedance for Down Devices

In the topology section device buffer strength target recommendations are different depending on the Topology and its configuration. If devices used do not have buffer strengths that match the target recommendations and do not have the ability to adjust the buffer strengths through software you can adjust the impedance via an external resistor as shown in [Figure 22-3](#). To determine R1 the formula is: $R1 = \text{Device Buffer Impedance Target} - \text{Actual Device Buffer Impedance}$.

Example:

- Device Drive Impedance Target = 80ohms
- Device Buffer Impedance = 45ohm
- $R1 = 80\text{ohm} - 45\text{ohm} = 35\text{ohm}$

Figure 22-3. SoundWire Device Drive Impedance Adjustment

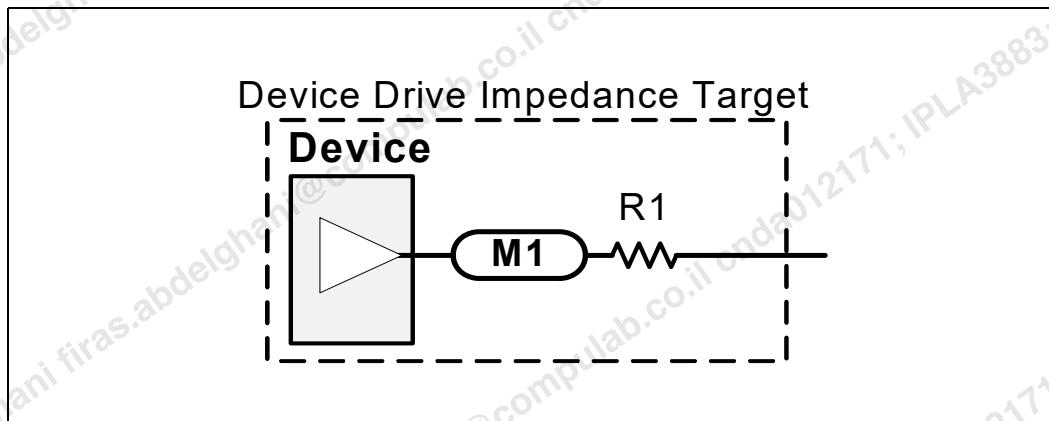


Table 22-4. SoundWire Device Drive Impedance Guidelines

Parameter ¹	Segment	Stack-up	Units	Recommendation
Trace Length Maximum	M1	MS	mils	393.7

1. Routes should be referenced to GND for entire route.

§ §



23 I²C* Interface Design Guidelines

PCH includes four I²C* controllers, providing four independent I²C interfaces. Each interface is a two-wire I²C serial interface consisting of a serial data line and a serial clock.

Each I²C interface supports standard mode (up to 100 Kb/s), fast mode (up to 400 Kb/s), fast mode plus (up to 1 Mb/s) and High speed mode (up to 3.2 Mb/s). Devices supporting standard mode and/or fast mode cannot be connected to the same I²C bus where devices supporting fast mode plus and/or High speed mode are connected.

The I²C interface can support 1.8 V or 3.3 V depending on devices connected to it.

For information on what OS the I²C interface supports, refer to the Intel® Serial I/O Driver PRD documentation.

23.1 I²C Platform Specific Important Information

Table 23-1. Reference Specifications

Title
I ² C Specification Version 5

23.1.1 I²C Signal Descriptions

23.1.1.1 Signal Groups

Table 23-2. I²C* Signals

Group	Signal Name	Description
Clock	I2C[3:0]_SCL	I ² C clock signals
Data	I2C[3:0]_SDA	I ² C data signals

23.1.2 I²C Topology Guidelines

23.1.2.1 General Design Considerations

I²C bus is a multi-device bus (i.e. more than one device can be connected to an I²C bus). The total number of devices connected to the bus is determined by the total capacitive load on the bus. The maximum bus capacitive load for each I²C bus is 400 pF and cannot be exceeded.

I²C clock and data signals require pull-up resistors. There is an internal pull-down resistor, and current assist which can be selected through registers based on the bus capacitive load including devices leakage currents (refer EDS for leakage current). See [Table 23-5](#) for recommendations on pull-up / pull-down resistors and current assist depending on bus capacitance and I²C speed mode.



Do not mix and match devices supporting 100 kHz / 400 kHz speed with the one supporting 1 MHz/3.2 MHz on the same I²C bus.

I²C signals are multiplexed with GPIOs and default to GPIO functionality (as input). If I²C interfaces are not used, the signals can be used as GPIOs instead. If the GPIO functionality is also not used, the signals can be left as no-connect.

23.1.2.2 Detailed Routing Requirements

The table below shows detailed routing requirement for I²C bus. Since I²C trace length is dependent on total capacitance of the bus, the designer needs to consider the number and types of I²C devices on each I²C bus. See table below for guidance on trace capacitance.

Table 23-3. I²C* Signal Routing Summary

Parameter	Routing Recommendation (in mils)	Routing Recommendation (in mm)
Trace Spacing between SCL and other signal (>1GHz)	15	0.381
Trace Spacing between SCL and other signal (>100MHz)	10	0.254
Trace Spacing between SCL and other signal (<1MHz)	5	0.127
Trace Spacing between SDA and other signal	5	0.127
Characteristic Impedance	30 to 70Ω	
Maximum number of Vias allowed	7	

Refer to [Chapter 2, "Stack-Up and PCB Considerations"](#) for other details like Trace Width, Trace Spacing, Breakout Width, Breakout Spacing etc.

I²C clock and data signals must be length matched within 1000 mils (25.4 mm).

System designers must consider the total bus capacitance which includes both package and device pin capacitance and board trace length capacitance when designing I²C bus. The total bus capacitance must not exceed 100 pF for High Speed Mode and 400pF for other modes (Standard/Fast/Fast mode plus). Tables below provides information to help determine total bus capacitance and proper internal pull-down resistor/current assist on the I²C buses.

Table 23-4. Bus Capacitance Reference Chart

Device	Capacitance Includes	Units	Capacitance
PCH Pin Capacitance	Pin Capacitance	pF	8 to 10
Device Pin Capacitance	Pin Capacitance	pF	5 to 10
Board Trace per Inch	per inch of trace length	pF	2 to 5

Trace Capacitance per inch is approximately equal to $85\sqrt{\epsilon_r} / Z_0$ (in pF) where, ϵ_r is Dielectric constant of material, Z_0 is Trace impedance

**Table 23-5. Bus Capacitance / Pull-Up and Current Assist Strength Settings**

I2C Standard Mode (100kHz) - Mode Pull-up / Pull-down /Pull down and Current Assist Strength Settings				
Total Bus Capacitance (C _b)	Internal Pull-up (Refer EDS)	External Pull-up	PCH Pull Down Strength (Refer EDS)	Current Assist
Upto 50pF	None	18kΩ	100Ω	None
Upto 100pF	None	10kΩ		None
Upto 200pF	None	4.7kΩ		None
Upto 300pF	None	3.3kΩ		None
Upto 400 pF	None	2.2KΩ		None
I2C Fast Mode (400kHz) - Mode Pull-up/ Pull-down Strength Settings				
Total Bus Capacitance (C _b)	Internal Pull-up (Refer EDS)	External Pull-up	PCH Pull Down Strength (Refer EDS)	Current Assist
Upto 50pF	None	5.6kΩ	100Ω	None
Upto 100pF	None	2.7KΩ		None
Upto 200pF	None	1.5KΩ		None
50pF to 300pF	None	1KΩ		None
50pF to 400pF	None	680Ω		None
I2C Fast mode Plus (1MHz) - Pull-up/Pull-down strength Settings				
Total Bus Capacitance (C _b)	Internal Pull-up (Refer EDS)	External Pull-up	PCH Pull Down Strength (Refer EDS)	Current Assist
Upto 50pF	None	2.2kΩ	100Ω	None
Upto 100pF	None	1.2kΩ		None
Upto 200pF	None	560Ω		None
Upto 300pF	None	390Ω		67Ω
Upto 400 pF	None	270Ω		50Ω
I2C High Speed mode -SDA (1.7MHz) Pull-up/Pull down and Current Assist strength Settings				
Total Bus Capacitance (C _b)	Internal Pull-up (Refer EDS)	External Pull-up	PCH Pull Down Strength (Refer EDS)	Current Assist
Upto 50pF	None	2.2kΩ	100Ω	None
50pF to 100pF	None	1.2kΩ		None
50pF to 200pF	None	560Ω		None
100pF to 300pF	None	330Ω		None
100pF to 400pF	None	270Ω		50Ω

**Table 23-5. Bus Capacitance / Pull-Up and Current Assist Strength Settings**

I2C High Speed mode -SCL (1.7MHz) at 1.8V Pull-up /Pull down and Current Assist strength Settings				
Total Bus Capacitance (C_b)	Internal Pull-up (Refer EDS)	External Pull-up	PCH Pull Down Strength (Refer EDS)	Current Assist
Upto 55pF	None	1.5kΩ	100Ω	000
45pF to 150pF	None	560Ω		000
100pF to 200pF	None	330Ω		000
150pF to 325pF	None	330Ω	50Ω	001
300pF to 400pF	None	330Ω		010
I2C High Speed mode -SCL(1.7MHz) at 3.3V Pull-up/Pull-down and Current Assist strength Settings				
Total Bus Capacitance (C_b)	Internal Pull-up (Refer EDS)	External Pull-up	PCH Pull Down Strength (Refer EDS)	Current Assist
Upto 55pF	None	1.5kΩ	100Ω	000
45pF to 150pF	None	560Ω		000
100pF to 200pF	None	330Ω		000
150pF to 275pF	None	330Ω	50Ω	001
200pF to 400pF	None	330Ω		010
I2C High Speed mode -SDA (3.2 MHz) Pull-up /Pull down and Current Assist strength Settings				
Total Bus Capacitance (C_b)	Internal Pull-up (Refer EDS)	External Pull-up	PCH Pull Down Strength (Refer EDS)	Current Assist
Upto 20pF	None	3.9kΩ	100Ω	None
20pF to 40pF	None	1.5kΩ		None
25pF to 60pF	None	1.2kΩ		None
30pF to 80pF	None	1kΩ		None
35pF to 100 pF	None	820Ω		None
I2C High Speed mode -SCL (3.2 MHz) at 1.8V Pull-up /Pull down and Current Assist strength Settings				
Total Bus Capacitance (C_b)	Internal Pull-up (Refer EDS)	External Pull-up (Refer EDS)	PCH Pull Down Strength	Current Assist
Upto 35pF	None	1.2kΩ	100Ω	000
30pF to 50pF	None	820Ω		000
45pF to 85pF	None	820Ω		001
80pF to 100pF	None	820Ω		010

**Table 23-5. Bus Capacitance / Pull-Up and Current Assist Strength Settings**

I2C High Speed mode -SCL (3.2 MHz) at 3.3V Pull-up /Pull down and Current Assist strength Settings				
Total Bus Capacitance (C _b)	Internal Pull-up (Refer EDS)	External Pull-up (Refer EDS)	PCH Pull Down Strength	Current Assist
Upto 35pF	None	1.2kΩ	100Ω	000
30pF to 50pF	None	820Ω		000
40pF to 70pF	None	820Ω		001
60pF to 100pF	None	820Ω		010

Note: Multiple options for Pull-up/pull-down and current assist strengths are provided for a particular Total bus capacitance. Choose the optimal value for system based on design considerations like power, BOM cost.

23.1.3 Tools

Intel does not promote any specific tool for this interface.

§ §

24

Universal Asynchronous Receiver Transmitter (UART) Interface Design Guidelines

24.1 UART Platform Specific Important Information

The platform integrates three Universal Asynchronous Receiver Transmitter (UART) controllers. Each supports up to 3.8 Mbit/s. The controllers can be used in the low-speed, full-speed, and high-speed modes. The controllers are based on the 16550 industry standard and communicates with serial data ports that conform to the RS-232 interface protocol.

For information on what OS the UART interface supports, refer to the Intel® Serial I/O Driver PRD documentation.

Note: Bluetooth* devices are not supported on the PCH UART interfaces.

24.1.1 UART Signal Descriptions

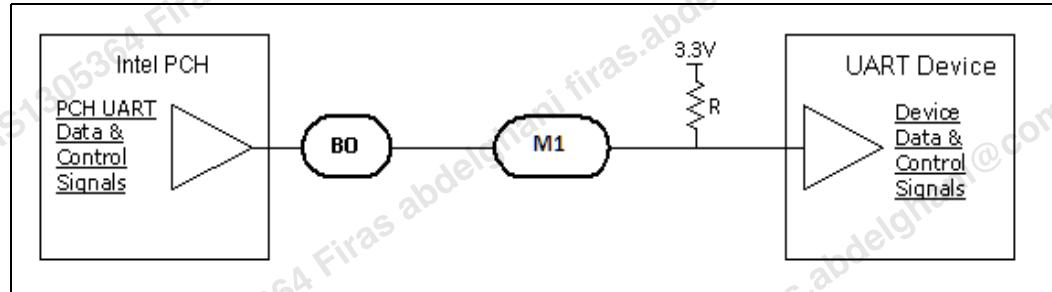
Table 24-1. UART Signals

Group	Signal Name	Description
Data	UART[2:0]_RXD	Receive Data Input signals
	UART[2:0]_TXD	Transmit Data Output signals
Control	UART[2:0]_RTS#	Request to Send signals
	UART[2:0]_CTS#	Clear to Send signals

24.1.2 UART Topology Guidelines

This section contains information and details for layout and routing guidelines for the UART interfaces.

Figure 24-1. UART Topology



**Table 24-2. UART Routing Guideline for Motherboard**

Parameter	Stack-up	Routing Recommendation (in mm)	Routing Recommendation (in mils)
M1 - Trace Length	MS/DSL	25-165	1000-6500
BO - Max Breakout Length	MS/DSL	12.7	500
Trace spacing between DATA and DATA	-	0.127	5
Maximum number of Vias			7

Refer to [Chapter 2, "Stack-Up and PCB Considerations"](#) for other details like Trace Width, Trace Spacing, Breakout Width, Breakout Spacing etc.

24.1.3 Tools

Intel does not promote any specific tool for this interface.

§ §



25 Generic Serial Peripheral Interface (GSPI)

25.1 GSPI Platform- Specific Important Information

The PCH's three generic SPI (GSPI) interfaces support devices which use SPI serial protocols for transferring data.

Each interface consists of 4 wires: a clock (CLK), two chip select (CS) and 2 data lines (MOSI and MISO).

The PCH generic SPI is full-duplex synchronous serial interface. The interface operates in master mode only, and supports serial bit rate up to 25Mb/s. Serial data formats may range from 4 to 32 bits in length.

Note that the GSPI is not the same as the PCH SPI interface for flash devices. This GSPI is used mainly for sensor support on the platform.

25.1.1 GSPI Signal Descriptions

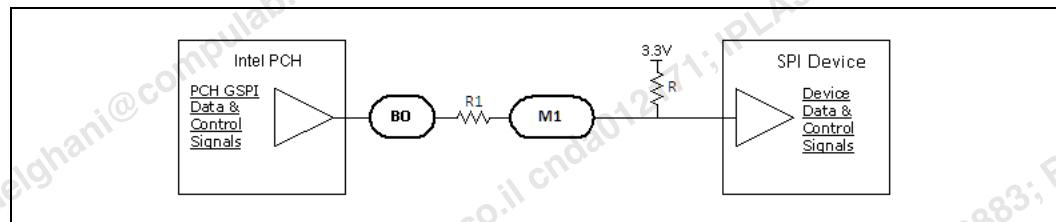
25.1.1.1 Signal Groups

Table 25-1. GSPI Signals

Group	Signal Name	Description
Clock	GSPI0_CLK GSPI1_CLK GSPI2_CLK	Clock signals
Data	GSPI0_MISO GSPI1_MISO GSPI2_MISO	Master In Slave Out signals
	GSPI0_MOSI GSPI1_MOSI GSPI2_MOSI	Master Out Slave In signals
Chip Select	GSPI0_CS0# GSPI0_CS1# GSPI1_CS0# GSPI1_CS1# GSPI2_CS0# GSPI2_CS1#	Chip select signals

25.1.2 GSPI Topology Guidelines

This section contains preliminary information and details for layout and routing guidelines for the generic SPI interfaces.

Figure 25-1. GSPI Topology

Series Resistor R1 mentioned in the above GSPI topology should have recommended value of 33 ohm if operated in 3.3V mode, else 0 ohm if operated in 1.8V mode.

R1 is recommended to be placed 12.7 mm (500 mils) from the PCH, but can be extended to 50.8mm (2000 mils) maximum if required. The length of breakout section BO is still 12.7 mm (500 mils) maximum

Table 25-2. GSPI Routing Guideline for CFL PCB

Parameter	Stack-up	Routing Recommendation (in mm)	Routing Recommendation (in mils)
M1 - Max Trace Length	MS/SL/DSL	203	8000
M1 - Trace Spacing between	MS/SL/DSL	Clock and others:0.381 Data and Data: 0.127	Clock and others:15 Data and Data: 5
BO - Max Breakout Length	MS/SL/DSL	12.7	500
Clock and Data Signal Length Mismatch	MS/SL/DSL	<12.7	< 500
R - Pull-up Resistor		- 50Kohms on GSPI[2:0]_CS[1:0]#, GSPI[2:0]_CLK and GSPI[2:0]_MISO - 150Kohms on GSPI[2:0]_MOSI if the default functional strap on the signal is desired (low), or 4.7Kohms pull-up resistor if the functional strap needs to be high.	
Maximum number of Vias allowed			7
Reference Plane			Continuous Ground

25.1.3 Debug Guidelines/Recommendations

GSPI signals are multiplexed with GPIOs and default to GPIO functionality. If GSPI interface is not used, the signals can be used as GPIOs instead. If the GPIO functionality is also not used, the signals can be left as no-connect.

25.1.4 Tools

Intel does not promote any specific tool for this interface.

§ §

26 Enhanced Serial Peripheral Interface (eSPI)

26.1 Introduction

The Enhanced Serial Peripheral Interface (eSPI) provides an alternative for connecting an EC to the platform (besides the LPC interface). Note that LPC and eSPI co-exist on the platform but only one interface can be enabled at a time via a hardware strap.

eSPI operates at 1.8V only and supports one slave device. This interface is not shared and distinct from the SPI interface used for flash device and TPM. The eSPI interface supports 20 MHz, 24MHz, 30 MHz, 48 MHz, and 60 MHz and up to Quad Mode.

Table 26-1. eSPI Signals

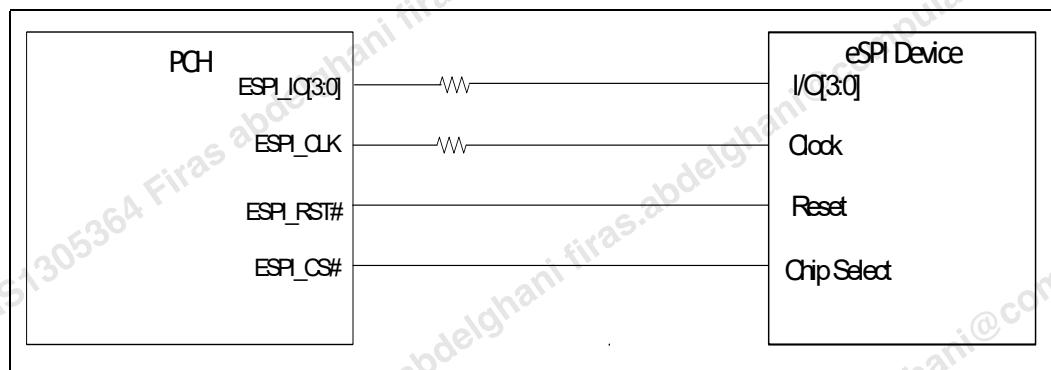
Signal Name	Group	Description
ESPI_IO[3:0]	Data	Bi-directional data signals used to transfer data between CFL and eSPI slave device
ESPI_CLK	Clock	eSPI Clock output from PCH
ESPI_CS0#	Control	eSPI chip selects
ESPI_RESET#	Control	eSPI reset signal

26.2 Topology and Guidelines

26.2.1 Topology

The eSPI interface supports single load topology or dual load as illustrated below.

Figure 26-1. eSPI Single Load Topology



26.2.2 Routing Guidelines

26.2.2.1 Single Load Topology Guidelines

Single load topology supports up to 60 MHz.

CS# and Reset signals do not require series resistors.

Figure 26-2. eSPI Single Load Topology

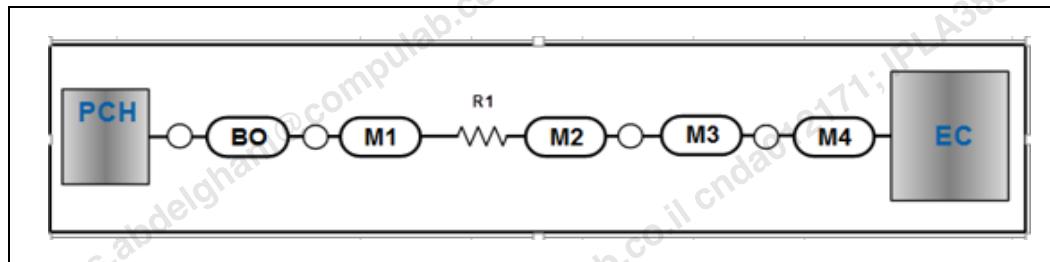


Table 26-2. eSPI Single Load Routing Guidelines

Segment / Parameter	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils			
				Segment	Total	Segment	Total		
BO	MS/SL	VSS	1	12.7	165.6	500	6519.69		
M1	MS	VSS	1	12.7		500			
M2	MS	VSS	0	0.5		19.69			
M3	MS/SL/DSL	VSS	1	127		5000			
M4	MS	VSS	1	12.7		500			
R1	For DATA lines: If BO+M1+M2+M3+M4 are full microstrip routing, R1 = 15 Ohm. Otherwise, R1 = 0 Ohm For Clock line: R1 = 33 Ohm R1 is recommended to be placed 12.7mm (500mils) from the PCH, but can be extended to 25.4mm (1000mils) if required								
Max Via Allowed	7								
Reference plan	Continuous ground only								

26.2.2.2 eSPI Length Matching and Spacing Requirement

- eSPI clock and eSPI data must be length matched to within 500 mils (12.7mm).
- eSPI clock and eSPI CS# must be length matched to within 1000 mils (25.4mm).
- Trace spacing between DATA and DATA is 5 mils (0.127mm)
- Trace spacing between CLK and other signals is 15 mils (0.381mm)



26.2.2.3 Other Design Considerations

26.2.2.3.1 Voltage Supply

The eSPI signals are multiplexed with Group A GPIOs (GPP_A). This signal group is powered by VCCPGPPA power pin. Since eSPI interface only supports 1.8V, the VCCPGPPA power pin must be connected to 1.8V when eSPI is utilized on the platform. Note that, in this case, all the signals in Group A GPIO (both as GPIO and native functionality) will operate at 1.8V. Designer should take this into account when designing the motherboard.

26.2.2.3.2 eSPI Design with 2 Chip Selects

On platforms designed with eSPI enabled and PCH SKU that supports 2 eSPI CS# (i.e. Intel® Z390 chipset), the following behavior needs to be taken into account:

- GPP_A7 / ESPI_ALERT0# and GPP_A0 / ESPI_ALERT1# pins default to ESPI_ALERT0# and ESPI_ALERT1# (native functions) with ~20K internal pull-ups.
- GPP_A6 / ESPI_CS1# pin defaults to ESPI_CS1# with ~20K internal pull-up before ESPI_RESET# deassertion and driven to logic high after ESPI_RESET# deassertion.

Depending on the number of chip select signals required, designers must follow the guidelines below:

- 1) If ESPI_CS1# is utilized to support 2 eSPI devices (i.e. ESPI_CS0#, ESPI_CS1#, ESPI_ALERT0#, and ESPI_ALERT1# are all used):
 - The eSPI/ EC Slave Device Enable soft strap needs to be configured to 1 (ESPI_CS1# is enabled)
 - No external termination is required on the pins
- 2) If ESPI_CS1# is NOT utilized (i.e. only ESPI_CS0# is used; ESPI_CS1#, ESPI_ALERT0#, and ESPI_ALERT1# are not used):
 - The eSPI / EC Slave Device Enable soft strap needs to be configured to 0 (ESPI_CS1# is disabled)
 - If GPP_A6 / ESPI_CS1#, GPP_A7 / ESPI_ALERT0# and GPP_A0 / ESPI_ALERT1# pins are not used, they can be left as no-connect.
 - If GPP_A6 / ESPI_CS1#, GPP_A7 / ESPI_ALERT0# and GPP_A0 / ESPI_ALERT1# pins are used as GPIO function:
 - For GPP_A7 / ESPI_ALERT0# and GPP_A0 / ESPI_ALERT1#, take into consideration that the internal pull-ups (~20K) on the pins are ON until they are programmed to GPIO function.
 - For GPP_A6 / ESPI_CS1#, there must NOT be any on-board device driving the pin to opposite value (low) before the signal is programmed to GPIO function. Also take into consideration that the internal pull-up (~20K) is ON until the signal is programmed to GPIO function.

§ §



27 SMBus 2.0/SMLink Interface Design Guidelines

27.1 SMBus 2.0/SMLink Platform Specific Important Information

27.1.0.1 SMBus Description

PCH integrates an SMBus 2.0 controller. The SMBus provides an interface to manage peripherals such as serial presence detection (SPD) on RAM, thermal sensors, PCI cards, etc. The slave interface allows an external micro controller to access system resources.

The SMBus interface on PCH uses two signals, SMBCLK and SMBDATA, to send and receive data from components residing on the bus. These signals are used by the SMBus Host, SMBus Slave, and TCO Controllers. These controllers reside inside PCH.

27.1.0.2 SMLink Description

PCH incorporates two SMLink interfaces, SMLink0 and SMLink1. When the integrated LAN controller is used, the SMLink0 is a dedicated bus between PCH's LAN controller and the PHY to improve performance and reliability. The SMLink1 is dedicated for an external controller (EC) or a Baseboard Management Controller (BMC). The BMC may communicate with PCH via SMLink1 and to the TCO logic through the Host SMBus signals.

SMBus and SMLink connectivity recommendations are described in [Figure 27-1](#) and [Figure 27-4](#) below.

Note:

The requirement to tie both SMLink and SMBus signals externally is not needed, as slave functionality is available on the SMBus pins.

27.1.1 SMBus 2.0/SMLink Signal Descriptions

27.1.1.1 Signal Groups

Table 27-1. SMBus and SMLink Signals

Group	Signal Names	Description
Clock	SMBCLK SML[1:0]CLK	SMBus/SMLink Clock signals
Data	SMBDATA SML[1:0]DATA	SMBus/SMLink Data lines
ALERT	SMBALERT# SML[1:0]ALERT#	SMBus/SMLink ALERT signals



27.1.2 SMBus 2.0/SMLink Topology Guidelines

27.1.2.1 General Design Considerations

- The maximum bus capacitance is 400 pF.
- SMBus devices that can operate in S3 must be powered by the suspend power supply.
- It is recommended that I²C devices (used on SMBus in I²C enabled mode) be powered by the core power supply. During an SMBus transaction in which the device is sending information to PCH, the device may not release the SMBus if PCH receives an asynchronous reset. Core well power is used to allow BIOS to reset the device if necessary. SMBus 2.0-compliant devices have a timeout capability which makes them insusceptible to this I²C issue, allowing flexibility in choosing a voltage supply.
- If SMBus is connected to PCI, it must be connected to all PCI slots.
- If SMBus is connected to PCI Express*, it must be connected to all PCI Express slots.

27.1.3 Detailed Routing Requirements

The following table shows detailed routing requirement for SMBus and SMLink signal. However since SMBus and SMLink trace length is dependent on total capacitance of the system bus, designer need to take into consideration the number and types of SMBus devices/slots on the motherboards.

External pull up is required which is also based on the load capacitance and bus speed. Details are captured in the following tables.

Designer need to calculate the total capacitance for trace routing and the pins of each device connected on the bus.

27.1.3.1 Length Matching Requirements

Data and clock signal for SMBus and SMLink signal to each device needs to be length matched to 1000 mils (25.4 mm).

**Table 27-2. SMBus Length Matching Summary**

Parameter	Routing Recommendation (in mils)	Routing Recommendation (in mm)
Trace Spacing between SCL and other signal (>1GHz)	15	0.381
Trace Spacing between SCL and other signal (>100MHz)	10	0.254
Trace Spacing between SCL and other signal (<1MHz)	5	0.127
Trace Spacing between SDA and other signal	5	0.127
Characteristic Impedance	30 to 70Ω	
Maximum number of Vias allowed	7	

27.1.4 SMBus and SMLink Connectivity Recommendation

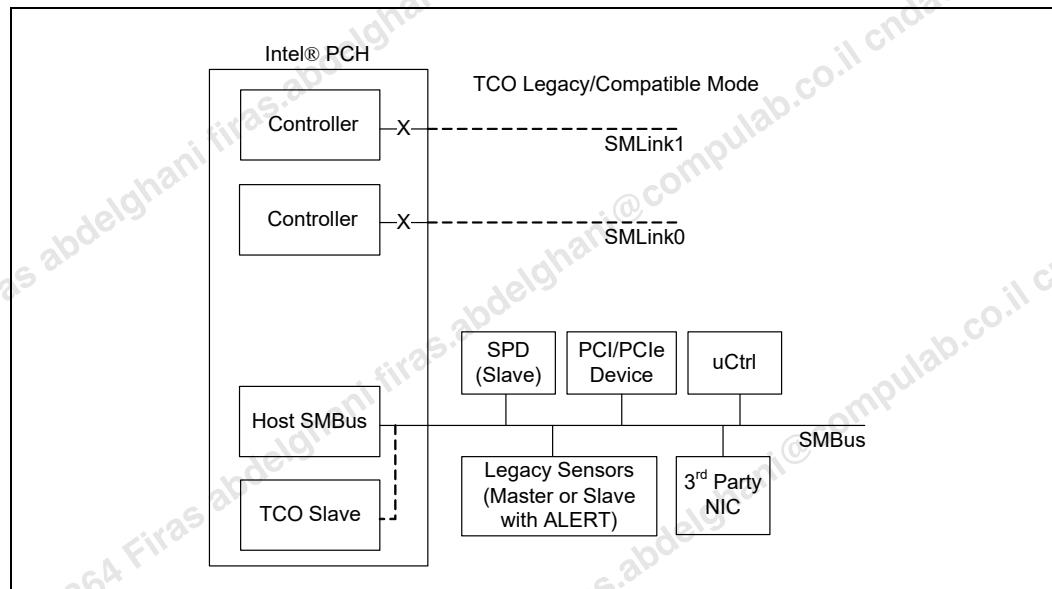
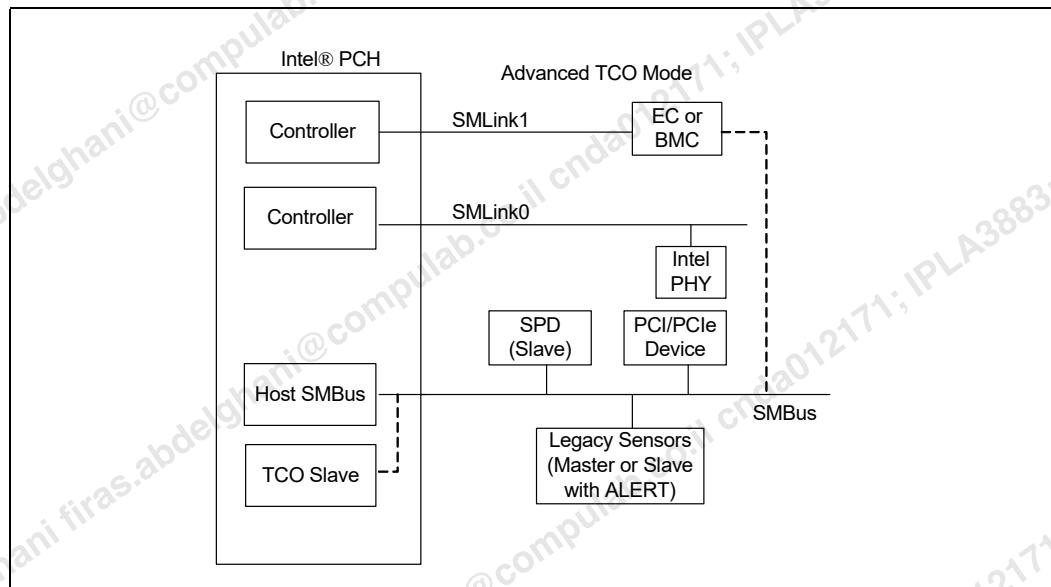
Figure 27-1. SMBus / SMLink (TCO Legacy Mode)

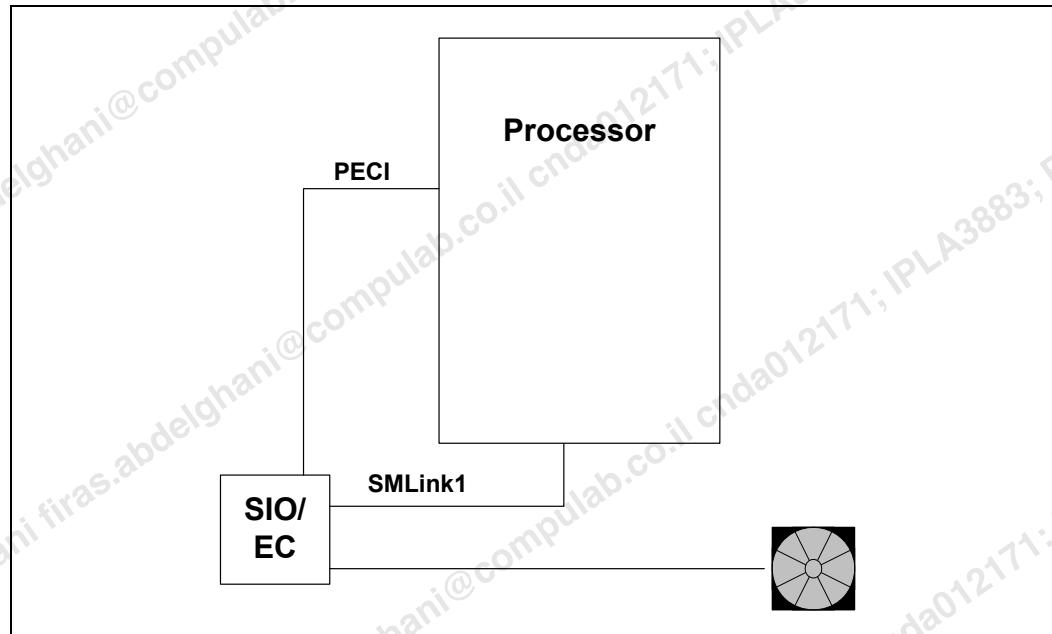
Figure 27-2. SMBus / SMLink Connectivity (Advanced TCO Mode)

27.1.4.1 Monitoring Integrated Sensors Over SMLink1

SMBus protocol is defined to allow compatible devices, e.g., SIO or Embedded Controller (EC), to monitor the integrated sensors in the chipset. This solution provides system thermal data to external controller such as the Embedded Controller (EC) or SIO, which can be used for fan speed control, chipsets temperature monitoring and/or managing other cooling elements. The EC or SIO can also get an alert when a device has gone out of its temperature limits.

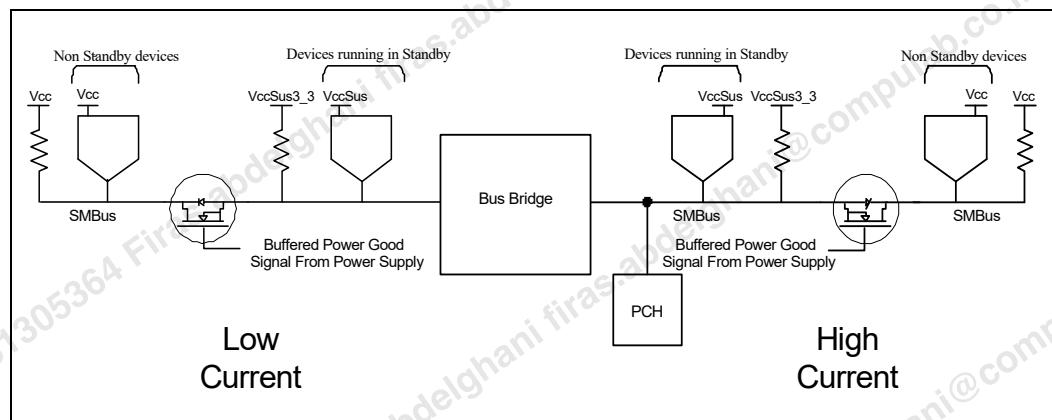
To implement this thermal monitoring over SMBus capability, the platform is required to have appropriate Intel® ME firmware and a compatible SIO/EC that supports the SMBus protocol.

The following figure illustrates the on board connectivity to support this capability.

**Figure 27-3. Connectivity for Thermal Monitoring over SMBus**

27.1.4.2 High Power/Low Power Mixed Architecture

This design allows for current isolation of high and low current devices while also allowing SMBus devices to communicate while in S3. Suspend power well leakage is minimized by keeping non-essential devices on the core supply. This is accomplished by the use of a "FET" to isolate the devices powered by the core and suspend supplies. See Figure below:

Figure 27-4. High Power/Low Power Mixed Vcc_SUSPEND / Vcc_CORE_ Architecture

Added Considerations for Mixed Architecture:

- The bus bridge must be powered by suspend power well.
- Devices that are powered by the suspend power well must not drive into other devices that are powered off. This is accomplished with the "bus switch".
- The bus bridge can be a device like the Philips* PCA9515.



27.1.5 Additional Guidelines

27.1.5.1 SMBus Design Considerations

No single SMBus design solution will work for all platforms. One must consider the total bus capacitance and device capabilities when designing SMBus segments. Routing SMBus to the PCI slots makes the design process even more challenging since they add a significant amount of capacitance to the bus. This extra capacitance has a large affect on the bus time constant which in turn affects the bus rise and fall times.

Primary considerations in the design process are:

- Device class (High/Low power). Most designs use primarily High Power Devices.
- Devices which must run in S3.
- Amount of suspend well current available, i.e., minimizing load of suspend power wells.

27.1.5.2 Calculating Physical Segment Pull-Up Resistor

The following tables are provided as a reference for deciding the value of the external pull-up resistor that should be used for a physical bus segment. If any physical bus segment exceeds maximum bus capacitance of 400 pF, then a bus bridge device like the Philips* PCA9515 must be used to separate the physical segment into two segments that individually have a bus capacitance less than the maximum bus capacitance.

Table 27-3. Bus Capacitance Reference Chart

Trace Capacitance per inch is approximately equal to $85\sqrt{\epsilon_r} / Z_0$ (in pF) where, ϵ_r is Dielectric constant of material, Z_0 is Trace impedance.

Device	Capacitance Includes	Units	Capacitance
PCH Pin Capacitance	Pin Capacitance	pF	8 to 10
Device Pin Capacitance	Pin Capacitance	pF	5 to 10
Board Trace per Inch	per inch of trace length	pF	2 to 5

**Table 27-4. Bus Capacitance/Pull-Up Resistor Relationship**

Standard Mode (100kHz) - Pull-up / Pull-down Resistor Settings		
Total Bus Capacitance (C_b)	External Pull-up	PCH Pull Down Strength (Refer EDS)
Upto 50 pF	18KΩ	100Ω
Upto 100 pF	10KΩ	
Upto 200 pF	4.7KΩ	
Upto 300 pF	3.3KΩ	
Upto 400 pF	2.2KΩ	
Fast Mode (400kHz) - Mode Pull-up/ Pull-down Strength Settings		
Total Bus Capacitance (C_b)	External Pull-up	PCH Pull Down Strength
Upto 50pF	5.6KΩ	100Ω
Upto 100pF	2.7KΩ	
Upto 200pF	1.5KΩ	
50pF to 300pF	1KΩ	
50pF to 400pF	680Ω	
Fast mode Plus (1MHz) - Pull-up/Pull-down strength Settings		
Total Bus Capacitance (C_b)	External Pull-up	PCH Pull Down Strength
Upto 50pF	2.2KΩ	100Ω
Upto 100pF	1.2KΩ	
Upto 200pF	560Ω	
Upto 300pF	390Ω	
Upto 400 pF	270Ω	

27.1.5.3 Intel® Trace Hub Backup: SMBus Test Points

Background: Intel Trace Hub is a new concept/mechanism, used to transport messages from the SoC to external monitor through a USB connector. This concept is defined as "Closed Chassis" message transport, without the need to open the chassis.

The Intel® ME is one of the entities using the Intel Trace Hub to provide debug data to the external monitor. However, since the Intel Trace Hub is a new technology, the following design guidelines act as a **backup** solution to route the debug information to an external SMBus Sniffer. **It is highly recommended that the SMBus Test Points are implemented**, so the customer or Intel debug team will be able to collect debug data from the system.



To quickly attach the SMBus sniffer to the platform, the following items should be added:

- Clearly marked (Silk-screen) SMBus test points, preferably, holes for 0.1" header (3 pins: SMBDATA, SMBCLK and GND), connected directly to the **SoC SMBus pins**.

Note: These Test points will be used to hook up to a SMBus sniffer that will impose an additional 60 pF load capacitance. The value of the SMBus external pull up resistor should be calculated with this additional 60 pF load to ensure that the sniffer and the SMBus will continue to operate normally when the sniffer is plugged in. If the total SMBus section capacitance is equal to or less than 400 pF after adding this 60 pF, no other change is required. In case the final SMBus section capacitance is larger than 400 pF, the SMBus will need a bridge to separate the bus into 2 sections with <400 pF capacitance each.

- Accessing the Test Points to hook the sniffer should be simple. It is recommended that the SMBus Test points be easily accessed when lifting the keyboard, or within the SSD or DDR compartments, or by removing existing battery, wireless or other available easy access panels on the chassis.

27.1.6 Compliance Requirements

Table 27-5. Compliance Documents

Title	Location
<i>System Management Bus (SMBus) Specification, version 2</i>	http://smbus.org/specs

27.1.7 Tools

Intel does not promote any specific tool for this interface.

§ §



28 Secure Digital Card with Extended Capacity (SDXC) Interface Design Guidelines

28.1 SDXC Signal Descriptions

Table 28-1. SDXC Signals

Group	Signal Name	Description
Clock	SD_CLK	SDXC Clock signal
Data	SD_DATA[3:0]	SDXC Data signals
Command	SD_CMD	SDXC Command signal
Control	SD_CD#	SD Card detect
	SD_WP	SD card write protect
Power Enable	SD_VDD1_PWR_EN#	SD card power enable 3.3V
Reference	SD_3P3_RCOMP	External Reference (200 Ohm +/- 1% pull down to ground)
	SD_1P8_RCOMP	External Reference (200 Ohm +/- 1% pull down to ground)

28.1.1 SDXC Topology Guideline

If the interface is used, external pull-up/pull-down resistors are not required on SD_DATA[3:0]; SD_CMD; SD_CD and SD_CLK.

Notes:

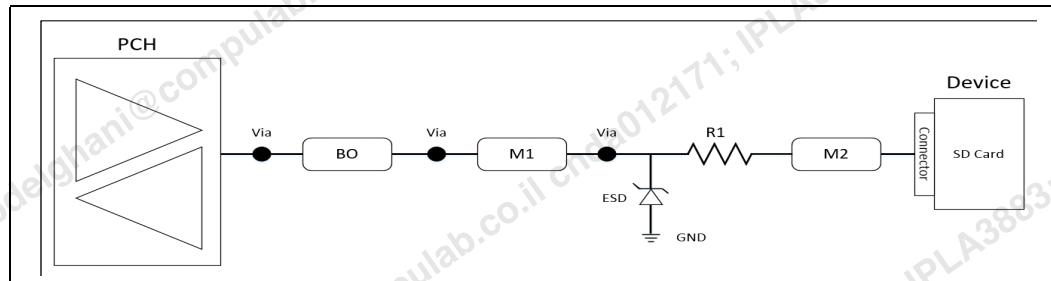
1. The topology and guidelines below apply to down device as well as M.2 connector.
2. Design guideline applies for 3.3V at 50MHz and 1.8V at 200MHz.
3. Transient Voltage Suppressor (TVS) may be required on SD_CMD, SD_DATA[0:3], SD_CLK and SD_CD#. Refer Section 49, "Electromagnetic Compatibility" for the same.

28.1.1.1 SDXC Topology Guidelines

The PCH implements a SDXC controller that supports SDXC 3.01 specifications.

The interface supports either 1.8V or 3.3V.

Resistor R1 (22 ohms) in the below topology diagram to be placed on SD_DATA[3:0] and SD_CMD not more than 12.7 mm away from the device.

Figure 28-1. SDXC Topology

Table 28-2. SDXC Routing Guidelines for CFL Motherboard

Parameter	Stack-up	Routing Recommendation (in mm)	Routing Recommendation (in mils)
BO - Max Breakout Length	MS/SL/DSL	12.7	500
M1 - Trace Length	SL/DSL	50-177	1968.5-6968.5
M2 - Max Breakin Length	MS	12.7	500
M - Trace Spacing for Clock Signal	NA	0.381	15
M - Trace Spacing between Data Signals	MS/SL	0.254	10
SD Card Clock and SD Card Data /CMD Signal Length Mismatch	MS/SL/DSL	<2.54 (Note 1)	<100 (Note 1)
Max Via Count for BO and M			4
Notes:			
1. Including package length is not required. 2. Break-in length must not have any via. 3. Reference should be continuous Ground plane only.			

Refer [Chapter 2, "Stack-Up and PCB Considerations"](#) for other details like Trace Width, Trace Spacing, Breakout Width, Breakout Spacing, etc.

Note:

SDXC signals are multiplexed with GPIOs and default to GPIO functionality (as input). If SDXC interface is not used, the signals can be used as GPIOs instead. If the GPIO functionality is also not used, the signals can be left as no-connect.

Warning:

SD_3P3_RCOMP and SD_1P8_RCOMP are Impedance Compensation for 3.3V and 1.8V operation of SDXC and GPIO buffers. External reference resistor is required (200 Ohm +/- 1% pull down to ground) regardless of SDXC being used or not. SD3_1P8_RCOMP and SD3_3P3_RCOMP can share a common RCOMP resistor of 200 Ohm, 1%. SD3_1P8_RCOMP and SD3_3P3_RCOMP can share a common RCOMP resistor of 200 Ohm, 1%.

28.1.1.2 SD_VDD1_PWR_EN Polarity

Signal SD card power enable (SD_VDD1_PWR_EN#) assertion logic can be changed by BIOS. In default BIOS implementation this signal has an Active High assertion logic.

§ §



29 Low Pin Count (LPC) Interface Design Guidelines

29.1 Overview

This document contains a design guidelines for a Low Pin Count bus interface, called LPC. The SoC contains LPC interfaces for legacy device support. LPC provides accesses to the BIOS Firmware Memory, Embedded Controller or Super I/O (Keyboard Controller, GamePort, Parallel Port, etc) and TPM (Trusted Platform Module).

29.2 LPC Signal Description

Table 29-1. LPC Signal Descriptions (Sheet 1 of 2)

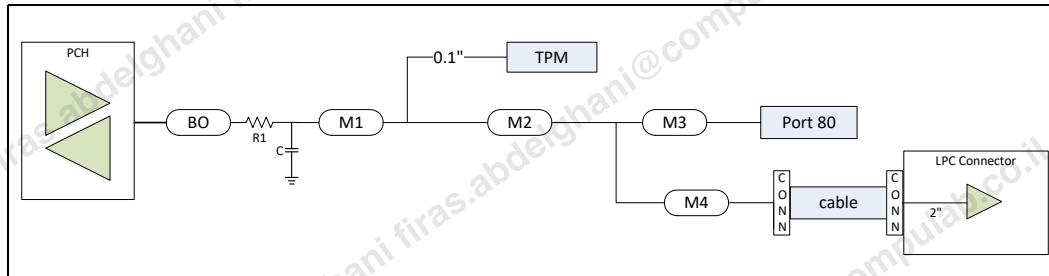
Signal Names	Group	Description
GPP_A1 / LAD0 / ESPI_IO0	Multiplexed Command, Address, Data (I/O)	This multiplexed signal line communicate address, control, and data information over the LPC bus between a host and a peripheral. Internal pull-ups are provided for these signals.
GPP_A2 / LAD1 / ESPI_IO1	Multiplexed Command, Address, Data (I/O)	This multiplexed signal line communicate address, control, and data information over the LPC bus between a host and a peripheral. Internal pull-ups are provided for these signals.
GPP_A3 / LAD2 / ESPI_IO2	Multiplexed Command, Address, Data (I/O)	This multiplexed signal line communicate address, control, and data information over the LPC bus between a host and a peripheral. Internal pull-ups are provided for these signals.
GPP_A4 / LAD3 / ESPI_IO3	Multiplexed Command, Address, Data (I/O)	This multiplexed signal line communicate address, control, and data information over the LPC bus between a host and a peripheral. Internal pull-ups are provided for these signals.
GPP_A5 / LFRAME# / ESPI_CS0#	Frame (O)	Indicates start of a new cycle and termination of a broken cycle
GPP_A0 / RCIN# / ESPI_ALERT1#	Input (I)	Keyboard Controller Reset Processor: The keyboard controller can generate INIT# to the processor. This saves the external OR gate with the PCH's other sources of INIT#. When the PCH detects the assertion of this signal, INIT# is generated to the processor. Note: An external Pull-up 10 KΩ to V3.3S power rail is required.
GPP_A9 / CLKOUT_LPC0 / ESPI_CLK	Clock (O)	Low Pin Count (LPC) Clock Outputs: Single-Ended 24-MHz output to various single load connectors/devices.
GPP_A10 / CLKOUT_LPC1	Clock (O)	Low Pin Count (LPC) Clock Outputs: Single-Ended 24-MHz output to various single load connectors/devices.

Table 29-1. LPC Signal Descriptions (Sheet 2 of 2)

Signal Names	Group	Description
GPP_A8 / CLKRUN#	Clock Run (I/O)	Input to determine the status of ILB_LPC_CLK and an open drain output used to request starting or speeding up ILB_LPC_CLK. This is a sustained tri-state signal used by the central resource to request permission to stop or slow ILB_LPC_CLK. The central resource is responsible for maintaining the signal in the asserted state when ILB_LPC_CLK is running and de-asserts the signal to request permission to stop or slow ILB_LPC_CLK. An internal pull-up is provided for this signal.
GPP_A6 / SERIRQ / ESPI_CS1#	Serial Interrupt Request (I/O)	This signal implements the serial interrupt protocol. Note: An external Pull-up 8.2 KΩ ~10 KΩ to V3.3S power rail is required.
GPP_A14 / SUS_STAT# / ESPI_RESET#	Output (O)	LPC Mode - Suspend Status: This signal is asserted by the PCH to indicate that the system will be entering a low power state soon. This can be monitored by devices with memory that need to switch from normal refresh to suspend refresh mode. It can also be used by other peripherals as an indication that they should isolate their outputs that may be going to powered-off planes.

29.2.1 LPC Topology Guidelines

29.2.2 LPC DATA 3 Load Daisy Chain Topology Guidelines

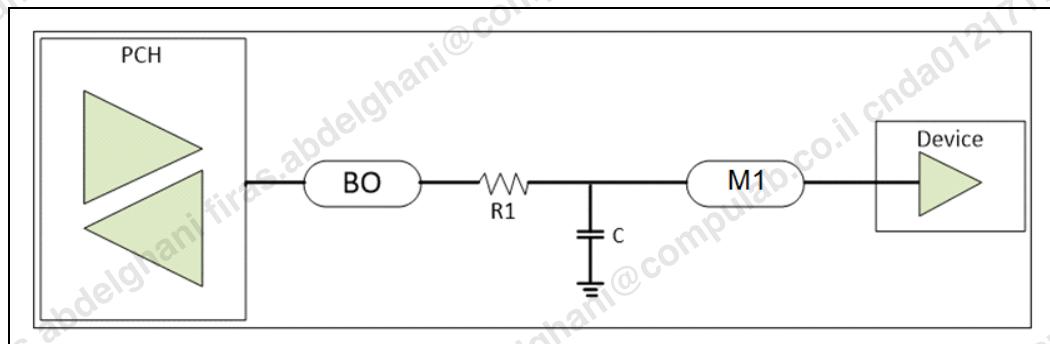
Figure 29-1. LPC DATA 3 Load Daisy Chain Topology

Table 29-2. Routing Guidelines for LPC DATA 3 Load Daisy Chain Topology (Sheet 1 of 2)

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mil	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	N/A	12.7	432.70	500	17035.44
M1	MS/SL/DSL	VSS	N/A	330		12992.13	
M2	MS/SL/DSL	VSS	N/A	64		2519.69	
M3	MS/SL/DSL	VSS	N/A	13		511.81	
M4	MS/SL/DSL	VSS	N/A	26		1023.62	
Cable	N/A	VSS	N/A	177.8		7000.00	

**Table 29-2. Routing Guidelines for LPC DATA 3 Load Daisy Chain Topology (Sheet 2 of 2)**

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils	
				Segment	Total	Segment	Total
Notes:							
1.	R1 is 0 ohm by default, can be up to 22 ohm if there is EMI issue. To be placed for all LPC DATA pins. EMI RC filter placeholder, refer to EMC section for details. R1 is recommended to be placed 12.7mm (500 mils) from the PCH, but can be extended to 25.4 mm (1000 mils) maximum if required. The length of breakout section BO is still 12.7mm (500 mils) maximum						
2.	C to be unstuffed by default, can be up to 27pF if there is EMI issue. EMI RC filter placeholder, refer to EMC section for details. C to be placed for all LPC DATA pins. C is recommended to be placed 12.7mm (500 mils) from the PCH, but can be extended to 25.4 mm (1000 mils) maximum if required. The length of breakout section BO is still 12.7mm (500 mils) maximum						
3.	Maximum 7 number of vias can be allowed.						
4.	Reference plane should be Continuous Ground Plane.						

29.2.3 LPC CLK Single Load Topology

Figure 29-2. LPC CLK Single Load Topology**Table 29-3. Routing Guidelines for LPC CLK Single Load Topology**

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	N/A	12.7	432.7	500	17035.43
M1	MS/SL/DSL	VSS	N/A	420		16535.43	

Notes:

1. R1 is 0 ohm by default, can be up to 22 ohm if there is EMI issue. EMI RC filter placeholder, refer to EMC section for details. R1 to be placed for LPC CLK pins. R1 is recommended to be placed 12.7mm (500 mils) from the PCH, but can be extended to 25.4 mm (1000 mils) maximum if required. The length of breakout section BO is still 12.7mm (500 mils) maximum.
2. C to be unstuffed by default, can be up to 27pF if there is EMI issue. C to be placed for LPC CLK pins. C is recommended to be placed 12.7mm (500 mils) from the PCH, but can be extended to 25.4 mm (1000 mils) maximum if required. The length of breakout section BO is still 12.7mm (500 mils) maximum
3. 7 number of vias can be allowed.
4. Reference plane should be only Continuous Ground Plane.

29.2.4 Disable Guidelines

If the LPC pins are not implemented on the platform, all the pins can be left as unconnected.



29.2.5

General Guidelines for Length Matching Requirements

1. For both P2P and branch topology, CLK length need to be matched with data length within 500 mils (12.7mm)
2. Trace spacing between DATA and DATA must be within 5 mils (0.127mm).
3. Trace spacing between CLK and other signals must be within 15 mils (0.381mm).

§ §



30 Serial Peripheral Interface (SPI0) Flash Design Guidelines

30.1 Overview

The Serial Peripheral Interface (SPI0) supports 2 SPI0 flash devices via 2 chip select (SPI0_CS0# and SPI0_CS1#). The maximum size of flash supported is determined by the SFDP-discovered addressing capability of each device. Each component can be up to 16 MB (32 MB total addressable) using 3-byte addressing. Each component can be up to 64 MB (128 MB total addressable) using 4-byte addressing. Another chip select (SPI0_CS2#) is also available and only used for TPM on SPI0 support.

PCH drives the SPI0 interface clock at either 20 MHz, 33 MHz, or 50 MHz and it will function with SPI0 flash devices that support at least one of these frequencies.

The SPI0 interface supports either 3.3V or 1.8V. Descriptor mode is required for all platforms with PCH.

A SPI0 flash device which supporting SFDP (Serial Flash Discovery Parameter) is required for all PCH design. A SPI0 flash device on SPI0_CS0# with a valid descriptor must be attached directly to the PCH.

Table 30-1. Acronyms

Acronyms	Description
CS	Chip Select
CLK	Clock
EC	Embedded Controller
FET	Field Effect Transistor
MISO	Master In Slave Out
MOSI	Master Out Slave In
SPI0	Serial Peripheral Interface
TPM	Trusted Platform Module

Table 30-2. SPI0 Signals (Sheet 1 of 2)

Signal Name	Group	Description
SPI0_MOSI	Data	SPI0 serial output data from PCH to the SPI0 flash device. This Pin will also function as Input during Dual and Quad I/O operation
SPI0_MISO	Data	SPI0 serial input data from the SPI0 flash device to PCH. This Pin will also function as Output during Dual and Quad I/O operation
SPI0_IO2	Data	SPI0 I/O to comprehend the support for the Quad I/O operation
SPI0_IO3	Data	SPI0 I/O to comprehend the support for the Quad I/O operation
SPI0_CLK	Clock	SPI0 Clock output from PCH
SPI0_CS0#	Chip Select0	SPI0 chip select 0
SPI0_CS1#	Chip Select1	SPI0 chip select 1 signal is used as the second chip select when 2 flash devices are used. Do not use when only one SPI0 flash is used

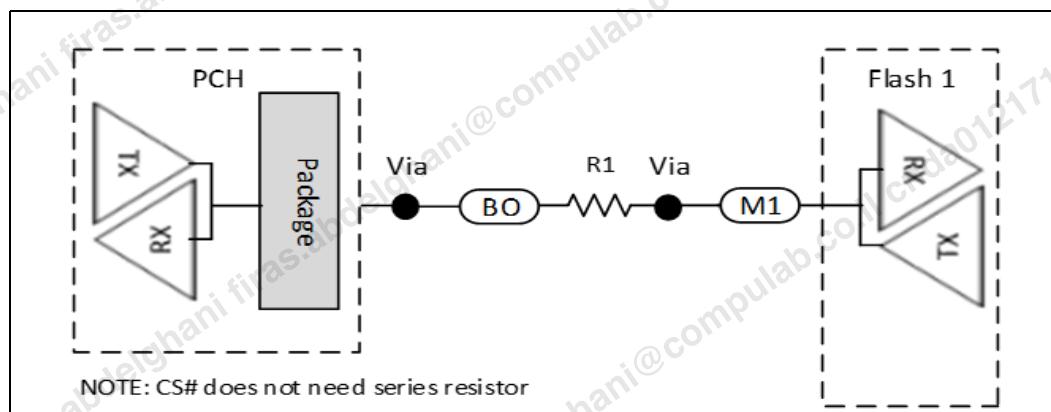
Table 30-2. SPI0 Signals (Sheet 2 of 2)

Signal Name	Group	Description
SPI0_CS2#	Chip Select2	Chip Select 2 is dedicated to support TPM on SPI0.

30.2 Serial Peripheral Interface (SPI0) Topology Guidelines

This section contains preliminary information and details for layout and routing guidelines for PCH SPI0 interface. SPI0 flash must be directly connected to the PCH SPI0 bus. Also, refer to the Serial Flash vendor documentation for additional Serial Flash specific design considerations.

30.2.0.1 SPI0 Single Load Topology Guidelines

Figure 30-1. SPI0 Single Load Topology

Table 30-3. Single Flash Topology Routing Guidelines

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	N/A	12.7	177.7	500.00	6996.06
				165		6496.06	

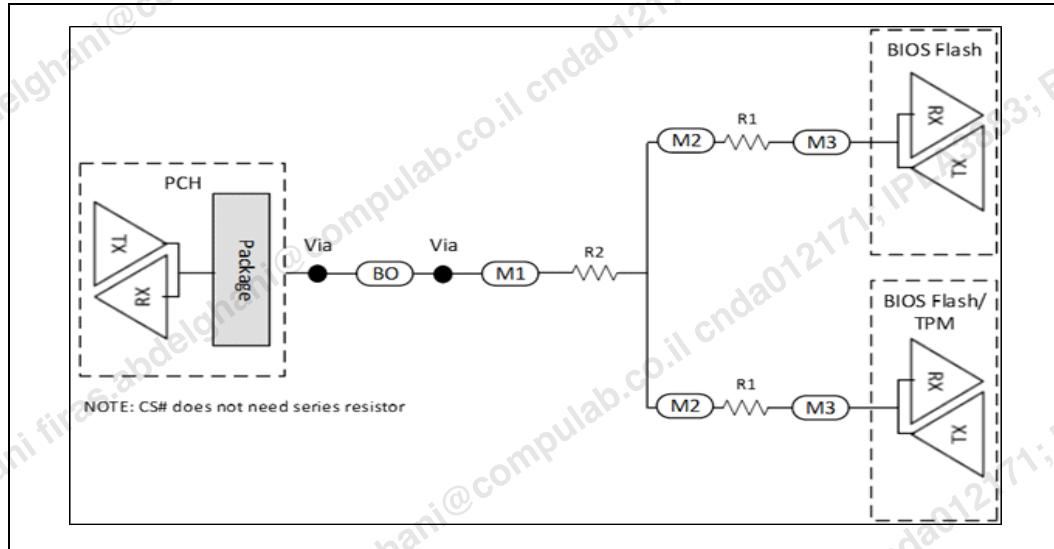
Notes:

1. R1 resistor should be stuffed with 33 ohm for 3.3V and 15 ohm for 1.8V. R1 is recommended to be placed 12.7mm (500 mils) from the PCH, but can be extended to 25.4 mm (1000 mils) maximum if required. The length of breakout section BO is still 12.7mm (500 mils) maximum. R1 is not required for CS# signal.
2. 5 number of vias can be allowed.
3. Continuous ground referencing plane
4. Design guidelines are applies for SPI0_IO_2 to 3, SPI0_MOSI, SPI0_MISO, SPI0_CLK, SPI0_FLASH_0_CS#, SPI0_FLASH_1_CS# and SPI0_TPM_CS#
5. Design guideline support up to 50MHz.



30.2.1 SPI0 2 Load Topology Guidelines

Figure 30-2. SPI0 2 Load Topology



The system can be configured with 1 SPI0 Flash and 1 TPM device.

Table 30-4. Routing Guidelines for SPI0 2 Load Topology Routing Guidelines

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
B0	MS/SL/DSL	VSS	N/A	12.7	177.7	500.00	6996.06
M1	MS/SL/DSL	VSS	N/A	124.46		4900.00	
M2	MS/SL/DSL	VSS	N/A	2.54		100.00	
M3	MS/SL/DSL	VSS	N/A	38		1496.06	

Notes:

1. R1 resistor should be stuffed with 33 ohm for 3.3V and 15 ohm for 1.8V. R1 is not required for CS# signal.
2. 5 number of vias can be allowed.
3. Continuous ground referencing plane
4. Design guidelines are applies for SPI0_IO_2 to 3, SPI0_MOSI, SPI0_MISO, SPI0_CLK, SPI0_FLASH_0_CS#, SPI0_FLASH_1_CS# and SPI0_TPM_CS#
5. Design guideline support up to 50MHz
6. R2 resistor should be stuffed with 5 ohm for 3.3V and 1.8V. R2 resistor is not required for CS# signal.

30.2.2 SPI0 2 Load with EC Flash sharing Topology

Figure 30-3. SPI0 2 Load with EC Flash sharing Topology

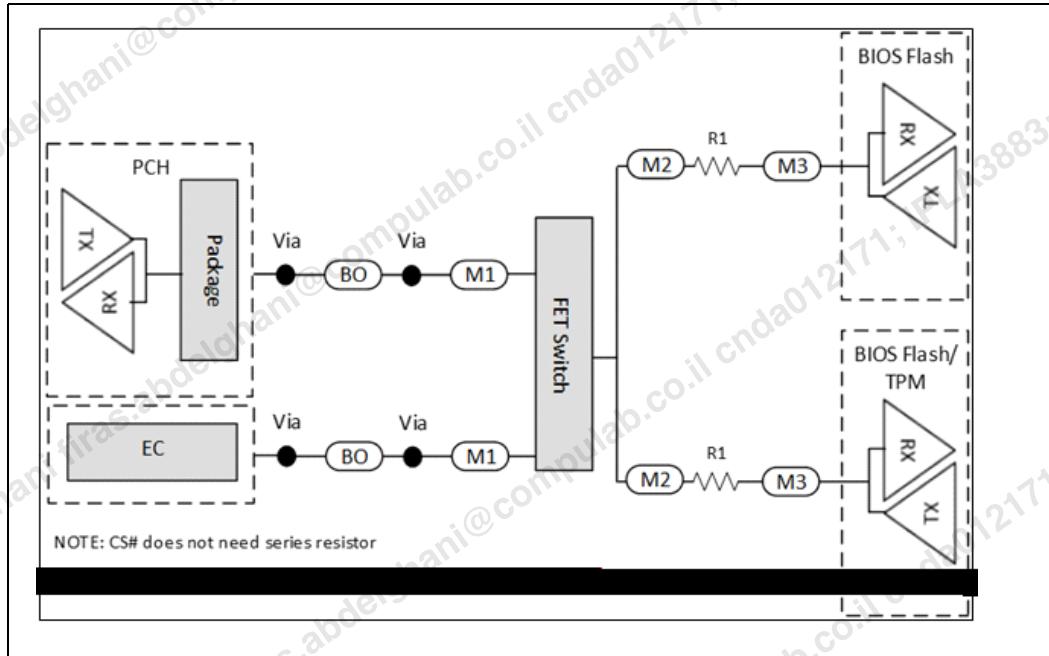
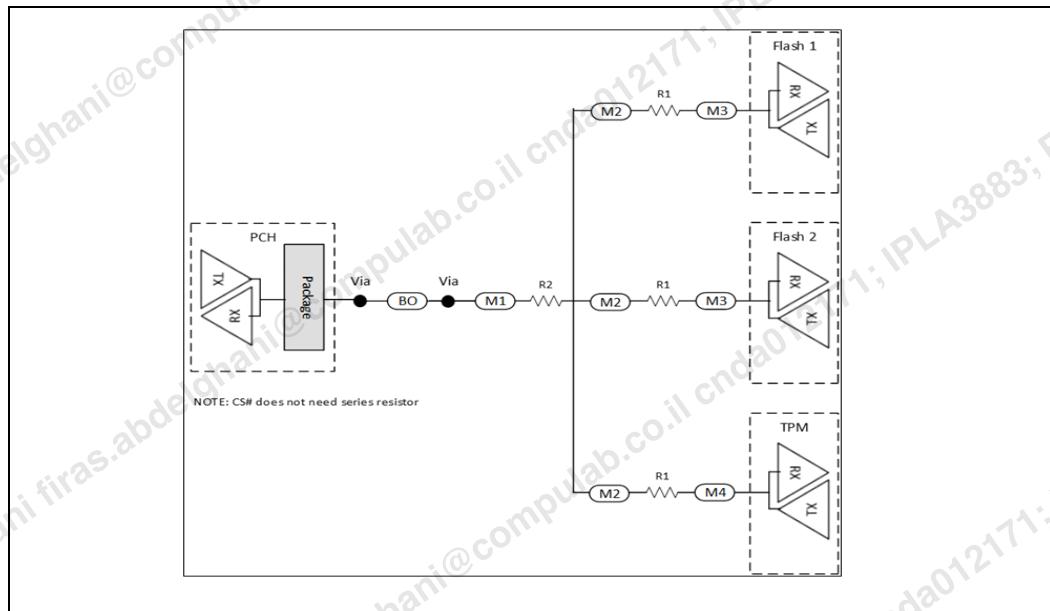


Table 30-5. Routing Guidelines for SPI0 2 Load with EC Flash Sharing Topology

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, mils			
				Segment	Total	Segment	Total		
B0	MS/SL/DSL	VSS	N/A	12.7	177.7	500.00	6996.06		
M1	MS/SL/DSL	VSS	N/A	124.46		4900.00			
M2	MS/SL/DSL	VSS	N/A	2.54		100.00			
M3	MS/SL/DSL	VSS	N/A	38		1496.06			
Notes:									
1. R1 resistor should be stuffed with 33 ohm for 3.3V and 15 ohm for 1.8V. R1 is not required for CS# signal.									
2. 5 number of vias can be allowed.									
3. Continuous ground referencing plane									
4. Design guideline support up to 50MHz									
5. Design guidelines applies for SPI0_IO_2 to 3, SPI0_MOSI, SPI0_MISO, SPI0_CLK, SPI0_FLASH_0_CS#, SPI0_FLASH_1_CS# and SPI0 TPM_CS#									
6. FET component criteria: Ron <5 ohm, Cin <3pF									

30.2.3 SPI0 3 Load Topology Guidelines

The PCH supports TPM through SPI0 bus. The topology below was a full configuration which consist of 2 SPI0 Flash and 1 TPM device.

**Figure 30-4. SPI0 3 Load Topology****Table 30-6. SPI0 3 Load Topology Routing Guidelines**

Segment	Trace Type	Reference	Via Count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
B0	MS/SL/DSL	VSS	N/A	12.7	189.70	500.00	7468.50
M1	MS/SL/DSL	VSS	N/A	124.46		4900.00	
M2	MS/SL/DSL	VSS	N/A	2.54		100.00	
M3	MS/SL/DSL	VSS	N/A	38		1496.06	
M4	MS/SL/DSL	VSS	N/A	50		1968.50	

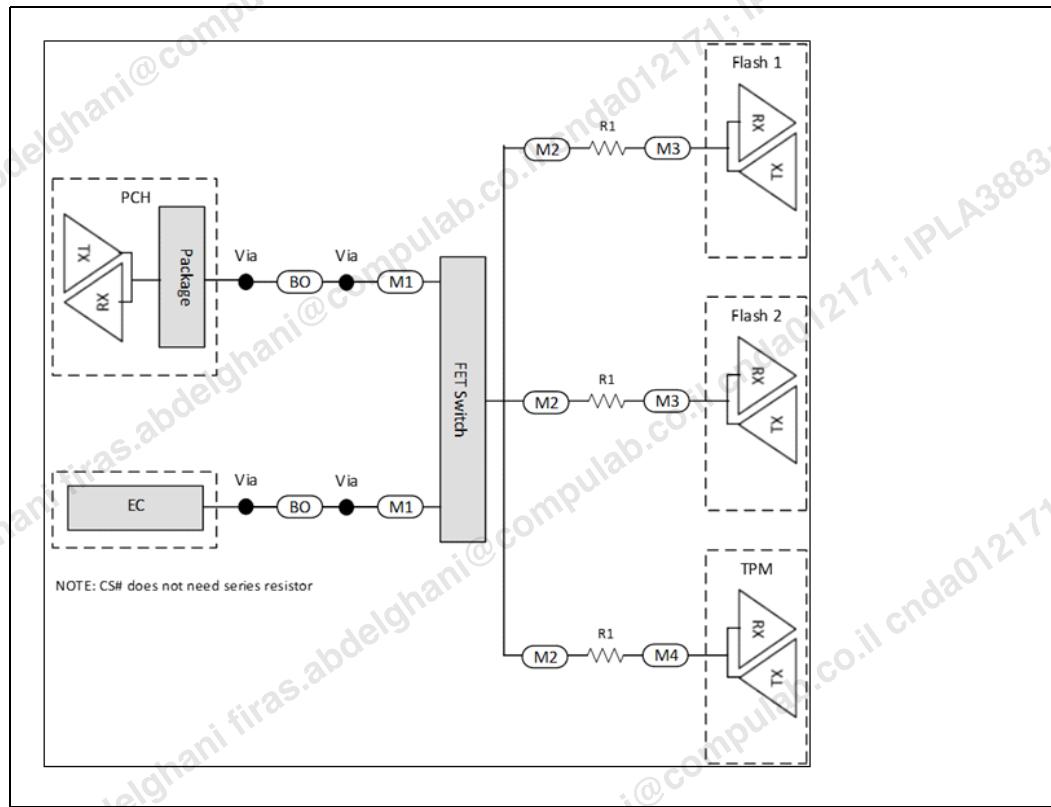
Notes:

1. R1 resistor should be stuffed with 33 ohm for 3.3V and 10 ohm for 1.8V. R1 is not required for CS# signal.
2. 5 number of vias can be allowed.
3. Continuous ground referencing plane.
4. Design guidelines are applies for SPI0_IO_2 to 3, SPI0_MOSI, SPI0_MISO, SPI0_CLK, SPI0_FLASH_0_CS#, SPI0_FLASH_1_CS# and SPI0_TPM_CS#
5. Design guideline support up to 50MHz
6. R2 resistor should be stuffed with 10 ohm for 3.3V and 1.8V. R2 resistor is not required for CS# signal.

30.2.4 SPI0 3 Load with EC Flash Sharing Topology

The PCH and Embedded Controller (EC) shares 2 SPI0 Flash device and TPM through FET switch. The topology below was a full configuration which consist of PCH, Embedded Controller (EC), 2 SPI0 Flash and 1 TPM device.

Figure 30-5. SPI0 3 Load with EC Flash Sharing Topology



30.2.4.1 SPI0 with Embedded Controller (EC) Flash Sharing Routing Guidelines

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, mils			
				Segment	Total	Segment	Total		
B0	MS/SL/DSL	VSS	N/A	12.7	189.70	500.00	7468.50		
M1	MS/SL/DSL	VSS	N/A	124.46		4900.00			
M2	MS/SL/DSL	VSS	N/A	2.54		100.00			
M3	MS/SL/DSL	VSS	N/A	38		1496.06			
M4	MS/SL/DSL	VSS	N/A	50		1968.50			
Notes:									
1. R1 Resistor should be 33 ohm for 3.3V and 10 ohm for 1.8V. R1 is not required for CS# signal.									
2. 5 number of vias can be allowed.									
3. Continuous ground referencing plane									
4. FET switch component criteria should be Ron <10 ohm, Cin <5pF									
5. Design guidelines are applies for SPI0_IO_2 to 3, SPI0_MOSI, SPI0_MISO, SPI0_CLK, SPI0_FLASH_0_CS#, SPI0_FLASH_1_CS# and SPI0_TPM_CS#									
6. Design guideline support up to 50MHz									



30.2.4.2 General guidelines for SPI0 Flash Device Interface

1. Length Matching between DATA and CLK should be maximum of 500 mils (12.7mm).
2. Trace spacing between DATA and DATA should be 10 mils (0.254mm)
3. Trace spacing between CLK and other signals should be 15 mils (0.381mm).

Notes:

1. SPI0 branches of segment M2 need to have length matching of 100 mils
2. SPI0_CLK and SPI0_MOSI (including all the Master Output Pins during Dual and Quad I/O Operation) must be length matched to within 500 mils
3. SPI0_CLK and SPI0_CSn# should be length matched by 500 mils, but can extend to 1000 mils.
4. SPI0_CLK must be 20 mils spacing from any other high frequency (>1GHz) signal

§ §



31 Serial Peripheral Interface (SPI1) Touch Design Guidelines

31.1 SPI1 Touch Platform Specific Important Information

The Serial Peripheral Interface (SPI1) supports 1 SPI1 Touch device via 1 chip select (SPI1_CS#) with Quad IO. PCH drives the SPI1 interface clock at 30 MHz and will function with SPI1 Touch device that support at this frequency.

The SPI1 interface supports either 3.3V or 1.8V. Descriptor mode is required for all platforms with PCH. A SPI1 Touch device on SPI1_CS# with a valid descriptor must be attached directly to the PCH.

31.2 SPI1 Touch Signal Descriptions

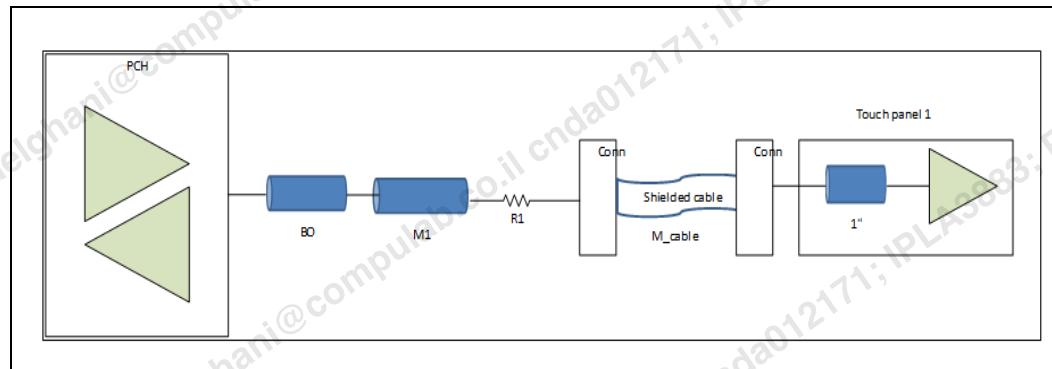
Signal Name Group Description	Signal Name Group Description	Signal Name Group Description
SPI1_CLK	Clock	SPI1 Clock output from PCH
SPI1_MISO_IO_1	Data	SPI1 serial input data from the SPI1 Touch Screen device to PCH. This Pin will also function as Output during Dual and Quad I/O operation
SPI1_MOSI_IO_0	Data	SPI1 serial output data from PCH to the SPI1 Touch Screen device. This Pin will also function as Input during Dual and Quad I/O operation
SPI1_IO_2	Data	SPI1 I/O to comprehend the support for the Quad I/O operation
SPI1_IO_3	Data	SPI1 I/O to comprehend the support for the Quad I/O operation
SPI1_CS#	Chip Select	SPI1 chip select

31.3 SPI1 Touch Topology Guidelines

This section contains preliminary information and details for layout and routing guidelines for PCH SPI interface. Touch device must be directly connected to the PCH SPI1 bus. Also, refer to the Serial Touch device vendor documentation for additional Serial Touch specific design considerations.



31.3.1 SPI1 Single Load Touch Topology



31.3.1.1 SPI1 Single Load Touch Length Matching Requirement

Table 31-1. SPI1 Single Load Touch Routing Guideline

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	N/A	12.7	462.7	500.00	18216.54
M1	MS/SL/DSL	VSS	N/A	300		11811.02	
M_Cable	Shielded cable	VSS	N/A	150		5905.51	

Notes:

1. Resistor R1 should be 10 ohm for 1.8V, 50 ohm for 3.3V. R1 is recommended to be placed 12.7mm (500 mils) from the connector. R1 recommendation for SPI1_CLK, SPI1_MOSI, SPI1_MISO, SPI1_IO_2 and SPI1_IO_3 signals
2. Design guideline support up to 30MHz.
3. 7 number of vias can be allowed.
4. Reference plane should be Continuous Ground Plane.
5. SPI1 Touch single load topology applies to SPI_CS#, SPI1_CLK, SPI1_MOSI, SPI1_MISO, SPI1_IO_2 and SPI1_IO_3

31.3.2 SPI1 Touch Length Matching Requirement

1. Length Matching between DATA and CLK should be maximum of 500 mils (12.7mm)
2. Trace spacing between DATA and DATA should be 5 mils (0.127mm).
3. Trace spacing between CLK and other signals should be 15 mils (0.381mm).

Notes:

1. SPI1_CLK and SPI1_MOSI (including all the Master Output Pins during Dual and Quad I/O Operation) must be length matched to within 500 mils.
2. SPI1_CLK and SPI1_CS# must be length matched to within 500 mils.
3. SPI1_CLK must be 20 mils spacing from any other high frequency (>1 GHz) signal.

§ §



32

Legacy Audio Interface Design Guidelines

Coffee Lake platform is a next-generation architecture for audio that allows audio output and input streams to be processed by the host IA processor or for processing to be offloaded from IA processing via the next generation Intel® Smart Sound Technology (Intel® SST) DSP.

This design guideline chapter includes the routing details for different legacy audio interfaces that connect to the Coffee Lake platform PCH. These are as follows:

- Intel® High Definition Audio (HD-A) Interface
- Digital Microphone (DMIC) Interface
- Integrated Interchip Sound (I²S) Interface

Intel® Display Audio Interface In this chapter th HD-A interface is compliant with Microsoft* Universal Audio Architecture (UAA). Contact your IHV (Independent Hardware Vendor) for information on HD-A, I2S, and DMIC based products.

32.1

Legacy Audio Interface Platform Specific Important Information

On the Coffee Lake platform the Intel HD Audio interface pins are partially multiplexed with I²S interface, and the MIPI SoundWire* interface and they can be configured as either (and in some cases simultaneously) for connection to end devices. The DMIC interface is multiplexed with various GPP signals. See the Coffee Lake PCH EDS for specific sku pins assignments and multiplexing details.

32.1.1

Legacy Audio Interface - Signal Description

Table 32-1. Audio Signals (Sheet 1 of 2)

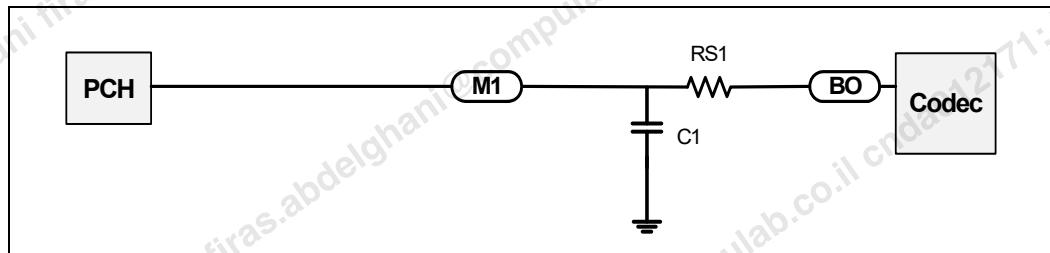
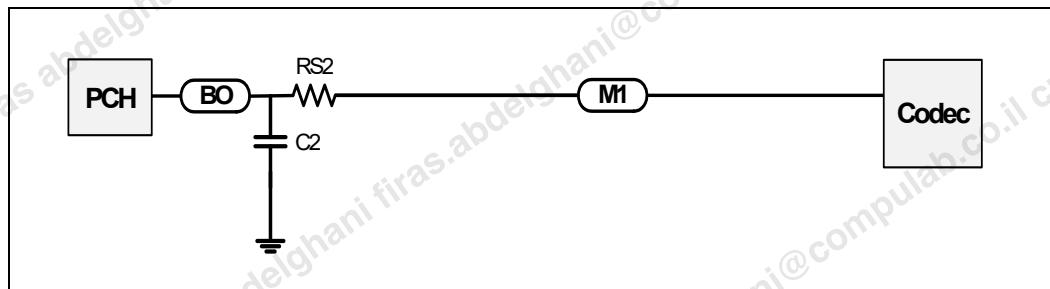
Signal Name	Description
Intel HD Audio Interface	
HDA_RST#	Master hardware reset to external codec(s)
HDA_SYNC	48 KHz fixed rate sample sync to the codec(s)
HDA_BCLK	24.000 MHz serial data clock generated by the Intel® HD Audio controller.
HDA_SDO	Serial TDM data output to the codec(s)
HDA_SDIN [1:0]	Serial TDM data inputs from the codecs
I2S Interface	
I2S_SCLK	I ² S Serial Bit Clocks for connection to I ² S devices.
I2S_TXD	I ² S Transmit Data (Serial data out) for connection to I ² S devices.
I2S_RXD	I ² S Receive Data (Serial data in) for connection to I ² S devices.
I2S_SFRM	I ² S Serial Frame for connection to I2S devices.
Intel® Display Audio Interface	

**Table 32-1. Audio Signals (Sheet 2 of 2)**

Signal Name	Description
HDACPU_SDI	Serial TDM data inputs from the integrated codec
HDACPU_SDO	Serial TDM data output to the integrated codec
HDACPU_SCLK	dedicated 24.000 MHz serial data clock to the integrated codec
DMIC Interface	
DMIC_CLK[1:0]	Serial data clock generated by the PCH to the digital microphone module
DMIC_DATA[1:0]	Serial data input from the digital microphone module

32.1.2 Intel High Definition Audio (Intel HD Audio) and DMIC Topology Guidelines

32.1.2.1 Intel HD Audio Single Load Audio Device Down Topology

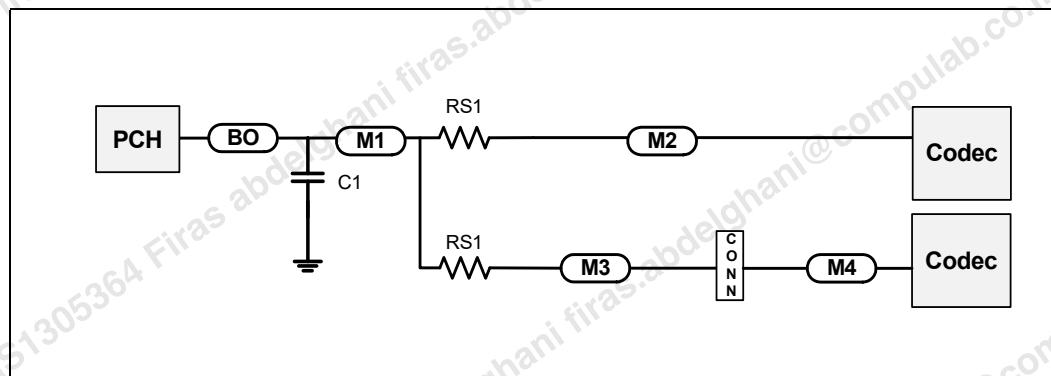
Figure 32-1. HDA_SDI Single Load Audio Down Topology**Figure 32-2. HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST# Audio Down Topology****Table 32-2. HDA_SDIN/HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST# Audio Down Routing Guidelines (Sheet 1 of 2)**

Parameter ³	Segment	Stack-up	Units	Recommendation
Trace Length Maximum	BO	MS/SL/DSL	mils	500
Trace Length Maximum	M1	MS/SL/DSL	mils	13976.38
Trace length Maximum	BO+M1	MS/SL/DSL	mils	14476.38
Trace Length Matching for HDA_BCLK and HDA_SDO	NA	NA	mils	500
Trace Spacing Between Data and Data	BO, M1	NA	mils	5
Trace Spacing Between Clk and other Signals	BO, M1	NA	mils	15
Rs Resistor Value ¹	RS1	NA	Ω	33

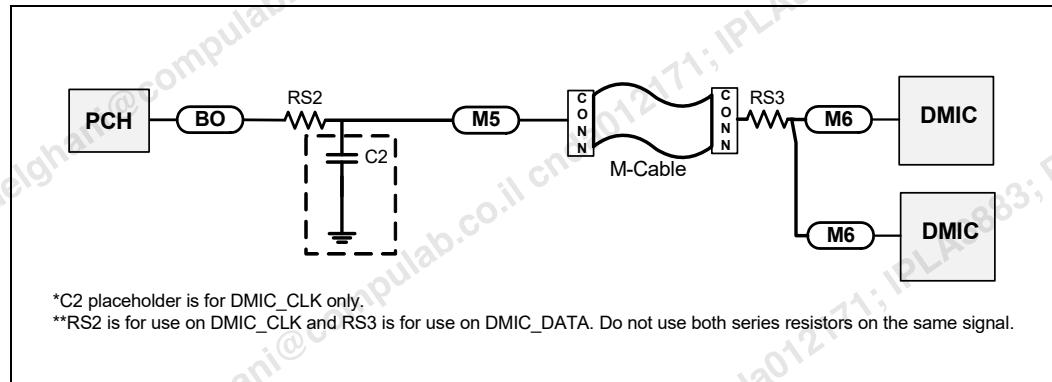
Table 32-2. HDA_SDIN/HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST# Audio Down Routing Guidelines (Sheet 2 of 2)

Parameter ³	Segment	Stack-up	Units	Recommendation
Rs Resistor Value ^{1,4}	RS2	NA	Ω	33
RS2 Resistor and C2 Capacitor Minimum Distance from PCH	M1	MS/SL/DSL	mils	500
RS2 Resistor Maximum Distance from PCH	M1	MS/SL/DSL	mils	3000
C1 Capacitor Max Distance from Codec	M1	MS	mils	500
C2 Capacitor Maximum Distance from PCH	M1	MS	mils	1000
C2 Capacitor Maximum Distance from PCH	M1	SL/DSL	mils	2000
Capacitor Recommended Value ²	C1, C2	MS	pF	2
Max Vias	NA	NA	count	7
PCH Buffer Impedance Target for Intel HD Audio ⁵	NA	NA	Ω	50
Note:				
1. This is Intel's general series resistor requirements from PCH to a typical end device. Please consult your codec vendor if any specific series resistor requirements for the end device is needed as it may vary from device to device.				
2. Capacitor to only be used for HDA_SDO, HDA_RST#, and HDA_SDIN for EMI purposes and should be a close as possible to the PCH.				
3. Routes should be referenced to GND for entire route.				
4. Resistor values should be 33 ohms for both 3.3v and 1.8v signaling.				
5. PCH buffer strength should be 50ohm, slew 11. Refer to EDS/BIOS programming guide for further details.				

32.1.2.2 Intel High Definition Audio (Intel HD Audio) and DMIC Branched Device Topology

Figure 32-3. HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST# Branched Topology


Note:
Any combination of above topology for the Intel HD Audio bus are valid but only up to 2 codec(s) are supported.

**Figure 32-4. DMIC_CLK and DMIC_DATA Branched Topology****Table 32-3. HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST#/DMIC_CLK/DMIC_DATA Branched Routing Guidelines (Sheet 1 of 2)**

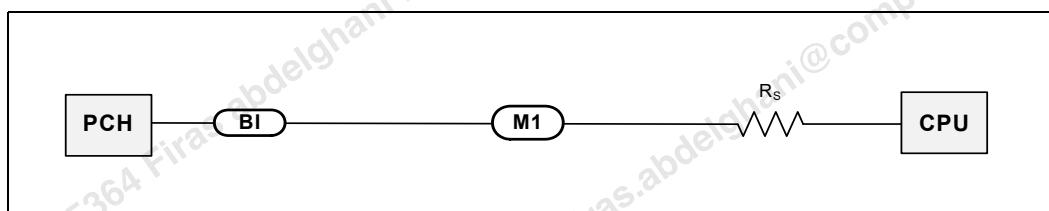
Parameter ³	Segment	Stack-up	Units	Recommendation
Trace Length Max	B0	SL	mils	500
Trace Length Max	M1, M3	MS/SL/DSL	mils	5000
Trace Length Max	M2	MS/SL/DSL	mils	8976.38
Trace Length Max	M4	MS	mils	3976.38
Trace Length Max	M5	MS/SL/DSL	mils	10000
Trace Length Max	M6	MS/SL/DSL	mils	5000
Trace Length Matching both Branch Lengths	M6	NA	mils	100
Trace Length Max	M-Cable	NA	mils	20000
Trace Length Max	B0+M1+M2 or B0+M1+M3+M4	MS/SL/DSL	mils	14476.38
Trace Length Max	B0+M5+M-Cable+M6	MS/SL/DSL	mils	35500
Trace Length Matching (HDA_BCLK and HDA_SDO)	NA	NA	mils	500
Trace Spacing Between Data and Data	B0, M1	NA	mils	5
Trace Spacing Between Clk and other Signals	B0, M1	NA	mils	15
HDA Resistor Value Max ²	RS1	NA	Ω	15
DMIC Resistor Value Max ⁷	RS2, RS3	NA	Ω	33
DMIC_CLK RS2 recommended distance from PCH ⁶	M5	MS	mils	500
DMIC_CLK RS2 max distance from PCH ⁶	M5	MS	mils	1000
DMIC_DATA RS3 recommended distance from DMIC	M6	MS	mils	500
C1 and C2 Recommended Distance from Output Device ⁶	M1, M5	MS/SL/DSL	mils	500
C1 and C2 Maximum Distance from PCH ⁶	M1, M5	MS	mils	1000

Table 32-3. HDA_SDO/HDA_SYNC/HDA_BCLK/HDA_RST#/DMIC_CLK/DMIC_DATA Branched Routing Guidelines (Sheet 2 of 2)

Parameter ³	Segment	Stack-up	Units	Recommendation
C1 Maximum Distance from Output Device ⁶	M1, M5	SL/DSL	mils	2000
DMIC spacing between DATA and DATA	NA	MS/SL/DSL	mils	5
DMIC spacing between CLK and other signals	NA	MS/SL/DSL	mils	15
Capacitor Value	C1	NA	pF	2
Capacitor Value ⁴	C2	NA	pF	27
Max Vias	NA	NA	count	7
PCH Buffer Impedance Target for HDA ⁵	NA	NA	Ω	33
Notes:				
1. HDA_SDO and HDA_BCLK as well as DMIC_CLK and DMIC_DATA must be length matched to within 500 mils.				
2. This is Intel's general series resistor requirements from PCH to a typical end device. Please consult your codec vendor if any specific series resistor requirements for the end device is needed as it may vary from device to device.				
3. Routes should be referenced to GND for entire route.				
4. DMIC_CLK cap can be just a placeholder and stuffed only when needed.				
5. PCH buffer strength should be 40ohm, slew 11. Refer to EDS/BIOS programming guide for further details.				
6. If M5 is routed on MS, EMI RC filter should be placed at the beginning of MS routing.				
7. RS2 is for use on DMIC_CLK and RS3 is for use on DMIC_DATA. Do not use both series resistors on the same signal.				

32.1.3 Integrated CODEC for Intel Display Audio

The processor has an integrated CODEC to provide Audio through HDMI/DP. The Intel Display Audio interface from the processor needs to be connected to the PCH as the audio communication is handled by Intel High Definition Audio controller in the PCH.

Figure 32-5. PROC_AUDIO_SDO to HDACPU_SDI (CPU Out, PCH In) Topology

Table 32-4. HDACPU_SDI Audio Down Routing Guidelines (Sheet 1 of 2)

Parameter	Segment	Stackup	Units	Routing Recommendation
Trace Length Maximum	BI/BO	MS/SL/DSL	mils	500
Trace Length Maximum	M1	MS/SL/DSL	mils	7500
Trace Length Maximum	M1+BI	MS/SL/DSL	mils	8000
Trace Length Matching with respect to HDACPU_SCLK	NA	NA	mils	500
Resistor Value	Rs	NA	Ω	20

**Table 32-4. HDACPU_SDI Audio Down Routing Guidelines (Sheet 2 of 2)**

Parameter	Segment	Stackup	Units	Routing Recommendation
PCH Buffer Impedance Target	NA	NA	Ω	50
Max Vias	NA	NA	Count	5

Figure 32-6. HDACPU_SDO to PROC_AUDIO_SDI/HDACPU_SCLK to PROC_AUDIO_CLK (PCH Out, CPU In) Topology**Table 32-5. HDACPU_SDO/HDACPU_SCLK Routing Guidelines**

Parameter	Segment	Stackup	Units	Routing Recommendation
Trace Length Maximum	BI, BO	MS/SL/DSL	mils	500
Trace Length Maximum	M1	MS/SL/DSL	mils	7500
Trace Length Maximum	BO+M1	MS/SL/DSL	mils	8000
Trace Length Matching with respect to HDACPU_SCLK	NA	NA	mils	500
Resistor Value	Rs	NA	Ω	30
PCH Buffer Impedance Target	NA	NA	Ω	50
Max Vias	NA	NA	Count	5

32.1.4 Disabling and Termination Guidelines for the Intel High Definition Audio Interface

When HDA_SDIN[1:0] is not implemented on the platform the signal pin(s) may be left unconnected.

When the Intel Display Audio interface is not implemented, PROC_AUDIO_CLK and PROC_AUDIO_SDI on the CPU need to be terminated to GND via a weak pull-down resistor (i.e. $\sim 2K\Omega$), PROC_AUDIO_SDO can be left unconnected. The Intel Display Audio pins on the PCH may be left disconnected.

32.1.5 I²S* Device Connection Topology

When the PCH Intel® HD Audio bus/I²S multiplexed pins are configured as I²S, the following topology and guidelines should be used for routing to end devices.

Figure 32-7. PCH to I²S* Device Topology - I2S_MCLK/ I2Sx_SFRM/ I2Sx_TXD/ I2Sx_RXD

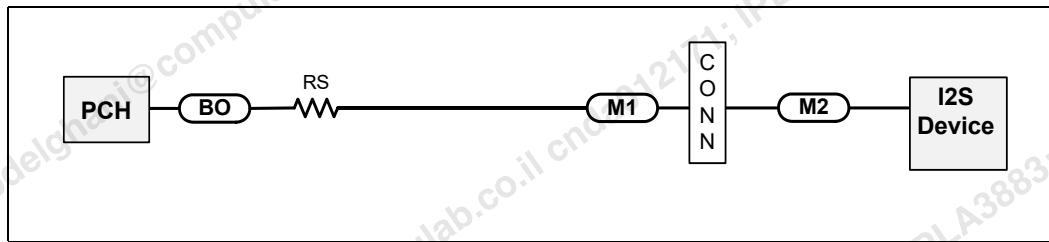


Table 32-6. I²S* Audio Down Routing Guidelines

Parameter ¹	Segment	Stack-up	Units	Recommendation
Trace Length Max	BO	MS/SL/DSL	mils	500
Trace Length Max	M1	MS/SL/DSL	mils	13066.9
Trace Length Max	M2	MS/SL/DSL	mils	1500
Trace Length Max	B0 + M1 + M2	MS/SL/DSL	mils	15066.93
Parallel Route Length	M1	DSL	mils	3000
RS Resistor Minimum Distance from PCH	M1	MS/SL/DSL	mils	500
RS Resistor Maximum Distance from PCH	M1	MS/SL/DSL	mils	1000
RS Series Resistor Max	RS	NA	ohms	33
Max number of Vias	NA	NA	count	7
PCH Buffer Impedance Target for I2S ²	NA	NA	Ω	50
Note:				
1. Parameters applies to I2S_MCLK, I2Sx_SFRM, I2Sx_SCLK, I2Sx_TXD, and I2Sx_RXD signals.				
2. PCH buffer strength should be 50ohm, slew 00. Refer to EDS/BIOS programming guide for further details.				

§ §



33 Intel® Management Engine (Intel® ME)

33.1 Acronyms

Acronyms	Description
C-Link, CLink	Controller Link
CFL	Coffee Lake
CNP	Cannon Lake PCH
DSW	Deep Sx Well
EC	Embedded Controller
FW	Firmware
LAN	Local Area Network
Intel® AMT	Intel® Active Management Technology
Intel® APS	Intel® Automatic Power Switch
Intel® ME	Intel® Management Engine
M0	Intel® ME power state. The host CPU is in S0 and Intel® ME is operational.
M3	Intel® ME power state. The host CPU is in Sx and Intel® ME is operational.
Moff	Intel® ME power state. The host CPU is in Sx and Intel® ME is not operational.
NIC	Network Interface Controller
SoC	System on Chip, the platform main processor.
SPI	Serial Peripheral Interface used for the Flash device interface, also name of the PCH interface to the real SPI flash
SUT	System Under Test
Sx	System state S3 or S4 or S5
TBD	To Be Defined
WLAN	Wireless LAN
WoL	Wake on LAN
WoWLAN	Wake on Wireless LAN

33.2 Preface

Intel® Management Engine (Intel® ME) is the SoC internal MinuteIA processor, running the Intel® ME firmware, to deal with platform management. It is connected to the Flash, loading Intel® ME and Intel® ISH FW, run the Intel® AMT section (where applicable), may control EC for power states transition and more. The following is the platform design guidelines, to support hardware design.

Unless otherwise indicated, this content pertains to Coffee Lake H platform.

33.3 Reference Documents

Document	Document Number
Converged Security and Manageability Engine (CSME) and Embedded Controller (EC) Interaction	573615

33.4 Introduction

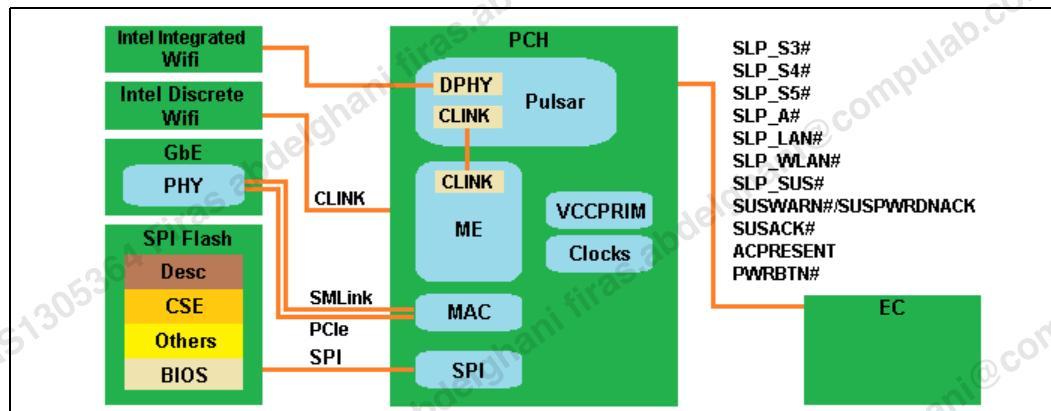
The following list of components compose the Intel® ME hardware infrastructure:

- Intel® ME is the general purpose controller, operating in parallel to, and is resource-isolated from the host processor and resides within the CNP-H (which is Cannon Lake PCH-H).
- The SPI Flash device stores firmware code for the Intel® ME and others.
- Intel® ME code is executed from system DRAM in S0 state. This code resides in UMA memory allocated by BIOS, which can be taken from any rank or channel. To interface with DRAM, the Intel® ME uses the main memory controller present in the processor. In S3 through S5 states, if the Intel® ME is active in those states (meaning, it is in M3), it uses internal RAM to the CNP-H (which is Cannon Lake PCH-H).
- The Intel® ME clock is provided by an internal ring oscillator in Sx/M3 states.
- It provides several sideband power sequencing signals, that should be used in conjunction with an EC for platform power flows.

Enabling Intel® ME on the Coffee Lake platform requires the following:

- Intel® ME to EC interface (at least minimal requirements)
- SPI flash

Figure 33-1. Intel® ME Architecture



33.5 Intel® ME Signal Descriptions

Intel® ME interacts with the on-board EC, to control system power state transitions.



33.5.1 Intel® ME to Embedded Controller Interface Signals

The Intel® ME subsystem in the CNP-LP must communicate with the EC to indicate when the Sx and DeepSx power wells need to remain on, to indicate when LAN and/or WLAN power are/is needed and to know the system power source (AC or battery) to make proper policy decisions. To allow this communication, several sideband signals are required between CNP-H and EC.

Note:

There is no on-board logic controlled by SLP_A# signal to power the Intel® ME. This signal is still provided externally to indicate whether Intel® ME is in Moff or not (so that the external devices may be powered accordingly)

33.6 Optimization Guidelines

33.6.1 Intel® ME Guidelines

In addition to basic component level support (CNP and SPI flash), there are two additional areas of board support that should be considered when designing with Intel® ME and Intel® ME applications. These two areas are the ability to access Intel® ME remotely (via LAN, Wireless LAN) and the ability for Intel® ME to support the M3 power state.

The hardware components for Intel® ME remote access are as following:

- Intel LAN (including SLP_LAN# signal support) is required for LAN connectivity for Intel® ME and supported applications.
- Intel Wireless LAN products (including SLP_WLAN# signal support) is required for wireless network connectivity for Intel® ME and supported applications.
 - The C-Link (Controller Link) is used to manage the wireless devices. C-Link is a 3-pin, 60-MHz, bi-directional, low-power bus that allows the CNP and WLAN subsystems to talk to each other. Refer to "Cannon Lake Platform Controller Hub (PCH-H) - External Design Specification (EDS) - Volume 1 of 2", RDC#571182 for full C-Link details.

To support the M3 power state:

- Support for power sequencing signals is described in the "Platform Power Sequencing Specification" chapter in this document.

Given different considerations, it is possible to design three different types of platforms:

- Platforms that support M3 power states **and** use the Intel LAN PHY or Intel wireless LAN solutions.
- Platforms that do not support M3 power states **and** use Intel LAN PHY or Intel wireless LAN PHY solutions.
- Platforms that do not support M3 power states **and** use a third-party LAN PHY solution.

The notes below in the following table summarize the power rails, enabling signals, and power state-by-state behavior that is common, or specifically relevant to M3 power state support and/or Intel LAN PHY / Wireless LAN usage.

**Table 33-1. Power Delivery Summary for Intel® ME SubSystem**

What It Powers	Rail	Sx / M3	Sx / Moff	Sx/Moff/ WoL	Enabled By	Power OK Indicator
Common						
Platform 5V rail	V5.0A	On	On	On	NA	NA
DRAM VDD	V1.35/V1.2	On in S3	On in S3	On in S3	SLP_S4#	NA
DRAM VTT	VDDQ/2	Off	Off	Off	SLP_S3#	NA
Coffee Lake processor	V1.0 VCC	Off	Off	Off	SLP_S3#	PCH_PWROK
M3 Support without Intel® LAN PHY/Wireless LAN Solution						
SPI interface	V1.8 or V3.3 VCCSPI	On	On	On	SLP_SUS#	RSMRST#
M3 Support + Intel® LAN PHY / Wireless LAN Solution						
LAN PHY	Power to the LAN PHY	On	Off	On	SLP_LAN#	NA
Wireless LAN Device	Power to the Wireless LAN Device	On	Off	On	SLP_WLAN#	NA
SPI interface	V1.8 or V3.3 VCCSPI	On	On	On	SLP_SUS#	RSMRST#
No M3 Support + Intel® LAN PHY / Wireless LAN Solution						
LAN PHY	Power to the LAN PHY	NA	Off	On	SLP_LAN#	NA
Wireless LAN	Power to the Wireless LAN Device	NA	Off	On	SLP_WLAN#	NA
SPI interface	V1.8 or V3.3 VCCSPI	On	On	On	SLP_SUS#	RSMRST#

Note: In Coffee Lake, Intel® ME Local RAM is powered by VCCSRAM_1P0 which is controlled by the platform. VCCSRAM_1P0 should be On in Sx/M3 and OFF in Sx/M-off

33.6.1.1 Intel® ME Wireless Controller Link

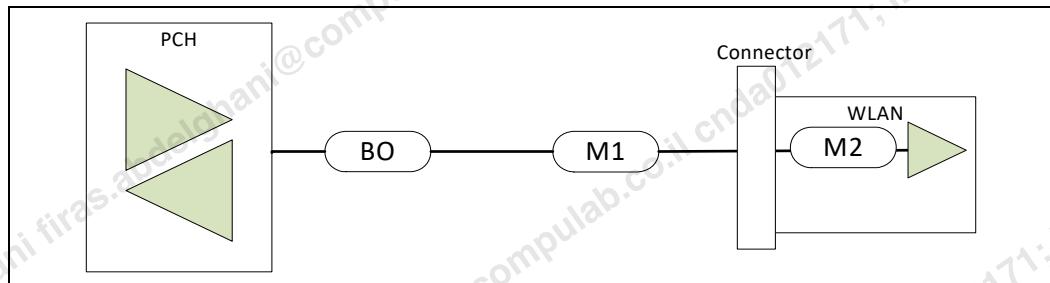
C-Link interface is the management communication link between the CNP-H and Intel Wireless cards. Correct operation of this bus is required for wireless network communication and wake up events.

CNP is designed for either an internal CLINK connection (for CNVi) or an external bus, as described in the rest of this section (also called "discrete connectivity"). The selection between these two configurations does not require any hardware changes at the board level. The Intel® ME configure its own C-Link multiplexer as to select the C-LINK configuration (internal/external). This feature allows another level of automation by allowing the Intel® ME controller to read a SoC/PCH internal bit, indicating if CNVi or discrete is currently connected.

For implementing the discrete connectivity, refer to "Connon Lake Platform Controller Hub (PCH-H) - External Design Specification (EDS) - Volume 1 of 2", RDC#566439 for full C-Link details.

**Table 33-2. Intel® ME C-Link Signals and Signal-Integrity Design Guidelines**

Group	Signal Name	Description
Clock	CL_CLK	Controller Link Clock: Bi-directional clock that connects to a Wireless LAN Device supporting Intel® Active Management Technology.
Data	CL_DATA	Controller Link Data: Bi-directional data that connects to a Wireless LAN Device supporting Intel® Active Management Technology.
Reset	CL_RST#	Controller Link Reset: Controller Link reset that connects to a Wireless LAN Device supporting Intel® Active Management Technology.

Figure 33-2. C-Link Topology - To WLAN (CL_CLK1, CL_DATA1, CL_RST#)**Table 33-3. C-Link Topology Guidelines**

Segment	Tline Type	Reference	Via Count	Max Length, mm	
				Segment	Total
BO	MS/SL/DSL	VSS	N/A	12.7	291.7
				241	
				38	

Table 33-4. C-Link General Guidelines

General Guidelines	
Length Matching between DATA and CLK	25.4mm
Trace spacing between DATA and DATA	0.127mm
Trace spacing between CLK and other signals	N/A
Max MLK_RSTB length	228 mm (~9")
Vias and Planes	
Number of vias allowed	5
Reference plane	Continuous Ground Only

LAN Considerations with or without Intel® Active Management (Intel® AMT) Support



33.6.2 For Intel® AMT support, Intel® ME Wake on LAN is a requirement.

33.6.2.1 Wake On LAN (WOL)

SLP_LAN# is used to indicate when power to the LAN PHY is needed. If Host Wake On LAN or Intel® ME Wake on LAN is enabled, the SLP_LAN# signal will remain high to keep power on to the LAN PHY.

The Integrated LAN (VccLAN) rail does not need to be powered in Sx/M-Off state unless they are needed as indicated by the CNP-H signals like SLP_S3# and SUSPWRDNACK.

33.6.2.2 Wake On Wireless LAN (WoWLAN)

SLP_WLAN# is used to indicate when power to the wireless LAN device is needed. If Host Wake on Wireless LAN is required in S3/S4/S5 or DeepSx states, the host BIOS must set HOST_WLAN_PP_EN. Refer to the "Cannon Lake Platform Controller Hub (PCH-LP) - External Design Specification (EDS) - Volume 2 of 2" document, RDC#565870, to the section discussing initialization of the HOST_WLAN_PP_EN bit. The SLP_WLAN# signal will remain high to keep power on to the wireless LAN device.

Note:

Unless controlled by system User, RF-Kill (W_DISABLE#) should not be asserted by the EC when power is provided to the WLAN card as this will block communication with the Intel® ME during M3 state.

33.6.3 WLAN Considerations with Intel® Active Management (Intel® AMT) Support

In designs where Corporate or Consumer Intel® ME are supported and wireless power management is supported, WLAN NIC power must be preserved in S0 and all its sub states (S0, S0ix, Connected standby and modern Standby).

33.6.4 SPI Flash Descriptor Security Override

To support Intel® ME, a SPI flash is required on the platform with sufficient space to hold system BIOS, Intel® ME firmware, Coffee Lake Intel® Integrated Sensor Solution firmware and any additional third party data storage. The SPI flash needs to be powered in states S0 through S5, independent of Intel® ME power state.

HDA_SDO_SSP0_TXD signal is used for Flash Descriptor Security Override (which is Intel® ME Debug Mode). This signal input should be tied to a jumper which connects the input to power through an external pull-up ($1\text{ K}\Omega \pm 5\%$) ONLY. When this signal is asserted, the Flash Security gets overridden for ease of image programming.

Customers are encouraged to implement this jumper - only on pre-productions designs, to be able to re-flash the SPI Flash device by customers technicians and/or by Intel Debug teams, when asking for their help. This jumper may be removed from the board design before final production.

33.7 Intel® APS

The Intel® APS is a tool that is used by the Intel® Platform Enablement Test Suite (Intel® PETS) tool. The Intel® PETS tool is used to test compliancy to Intel® ME requirements and is a validation vehicle to assist with the reproduction of power



management and power sequencing issues. The Intel® APS signals are required to be present at an accessible location on the board. Routing these signals to a connector is strongly recommended and will contribute significantly to accelerating debug and system validation. If an Intel® PETS run is fully done on pre-production SUT, the Intel® APS connector may be removed from the production system board layout.

An Intel® APS header allows for easy connection to a platform without extensive rework and/or intrusion by grouping signals required by the Intel® APS to a common connector. It is strongly recommended to use one of the two proposed connector options described below.

The first option is to use a 18-pin Flat Flex Cable (FFC)/Flexible Printed Circuitry (FPC) connector, such as the 10051922-1810elf. It's a Lower Side Contact, Side Entry, Surface Mount ZIF Connector with 0.5 mm pitch. The pinout of the ZIF connector is shown in [Table 33-5](#). This ZIF connector should be placed in an accessible location for accessing it without opening the chassis. It could be somewhere under the mobile system keyboard or inside the SSD/DDR module compartment. The keyboard or the SSD/DDR back cover could be lifted and the FFC/FPC could be plugged into the proposed ZIF connector, as shown in [Figure 33-3](#), [Figure 33-4](#) and [Figure 33-5](#). After well placing the Intel® APS adapter, all the necessary Intel® APS signal lines can be connected to the 18-pin 0.1" (2.54 mm) header of Intel® APS Adapter, as shown in [Figure 33-6](#). Please contact Intel representative for information of the Intel® APS Adapter and the FFC/FPC.

Figure 33-3. Location of ZIF connector, FFC/FPC and Intel® APS Adapter

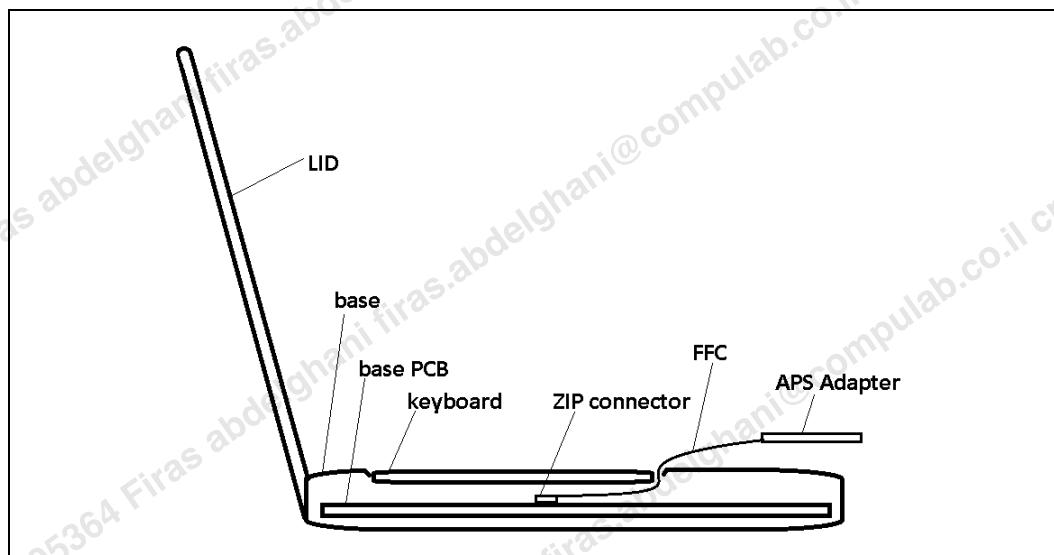
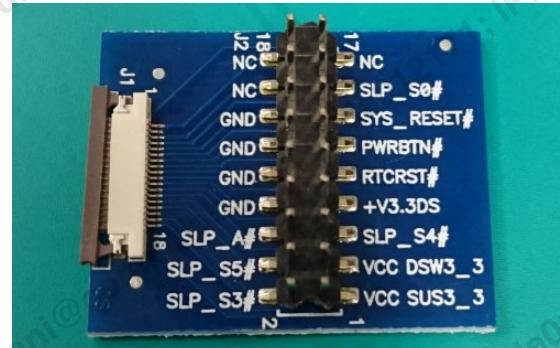
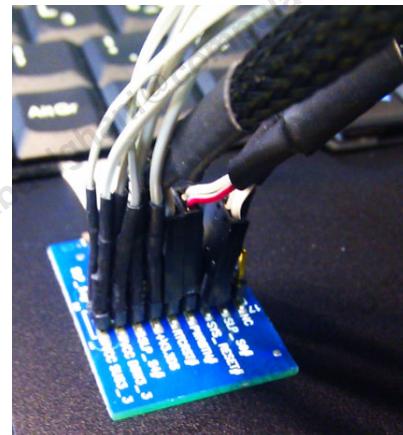


Figure 33-4. An Intel® Automatic Power Switcher (Intel® APS) Adapter with a FFC



Figure 33-5. An Intel® Automatic Power Switcher (Intel® APS) Adapter**Figure 33-6. Intel® Automatic Power Switcher (Intel® APS) Adapter connected**

The second connector option is to use a single 18-pin (2 rows of 9 pins) male header with pin width of 0.64 mm, pin height of 5.84 mm and a 2.54 mm distance (pitch) between pins, as shown in [Figure 33-7](#). The pin-out of the 18-pin male header is shown in the [Table 33-5](#). These pins can be connected directly to Intel® APS. The Intel® APS Adapter is not necessary.

When system gets to the production stage, and if the Intel® ME subsystem is fully functional and is fully validated on pre-production systems, the Intel® APS connector may become "UN_STUFF" (meaning, not being placed on the board). It is recommended to leave the footprint of Intel® APS connector with 'APS' label on silk screen next to the footprint on the system board. Please be noted to solder down the Intel® APS connector to the footprint if the system is going to be sent to Intel for Intel® ME sub-system debugging.



Figure 33-7. Intel® APS Connector

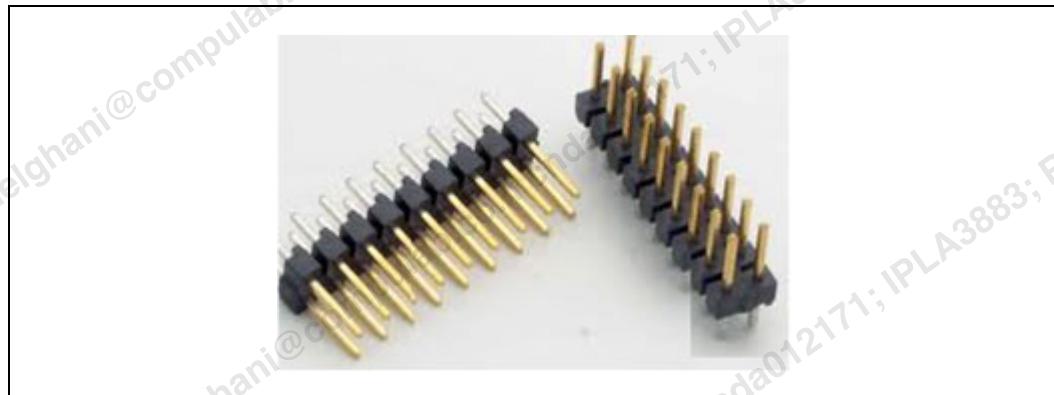


Table 33-5. Intel® Automatic Power Switcher (Intel® APS) Connector

Pin	Signal Name	Description	Intel® APS Signal Name
1	VCCPRIM_3P3	3.3V Primary Power Well	SUS
2	GPD_4_SLP_S3#	When asserted (0) system is in S3	S3
3	NC	No Connection	
4	GPD_10_SLP_S5#	When asserted (0) system is in S5	S5
5	GPD_5_SLP_S4#	When asserted (0) system is in S4	S4
6	GPD_6_SLP_A#	When asserted (0) Intel® ME is in Moff	M1/OFF
7	VCCDSW_3P3	Used to determine if the system is in Deep S4/S5	INEX1
8	GND	Ground	GND
9	RTCRST#	When asserted (0) CMOS is cleared	
10	GND	Ground for RTCRST#	
11	PWRBTN#	When asserted (0) Power Button pushed	PWR B
12	GND	Ground for PWRBTN#	PWR B GND
13	SYS_RESET#	When asserted (0) Reset Button pushed	RST B
14	GND	Ground for SYS_RESET#	RST B GND
15	GPP_B12_SLP_S0#	When asserted (0) system is in deterministic idle state	
16	NC	No Connection	
17	NC	No Connection	
18	NC	No Connection	

Table 33-6. Pin Location for Dual-in-Line Connector

Signal Name	Pin	Header	Pin	Signal Name
VCCPRIM_3P3	1		2	GPD_4_SLP_S3#
NC	3		4	GPD_10_SLP_S5#
GPD_5_SLP_S4#	5		6	GPD_6_SLP_A#
VCCDSW_3P3	7		8	GND
RTCRST#	9		10	GND for RTCRST#
PWRBTN#	11		12	GND for PWRBTN#
SYS_RESET#	13		14	GND for SYS_RESET#
GPP_B12_SLP_S0#	15		16	NC
NC	17		18	NC

Notes:

1. The unused or unconnected signal sampling lines which are INEX3 to INEX5 from the Intel® APS are better to be connected to GND for preventing unexpected measurement results or risk. Without connecting these unused lines to GND, it is possible to damage the Intel® APS hardware. Because of this, it is strongly recommended to provide additional GND pins for the unused INEX sampling lines. For systems that do not implement Deep Sx, five additional GND pins are needed. For systems that do implement Deep Sx, only three additional GND pins are needed.
2. If neither of the two options above is applicable, the Intel® APS signals should be routed to solder pads located near the memory or SSD slots. Therefore the



required signals on a laptop form factor can be easily accessed through the self-service door on the bottom of the platform.

3. It is strongly recommended that the name 'APS' should be labeled on silk screen next to the Intel® APS connector or Intel® APS test pads, and each pin name clearly marked on silk screen on the PCB.

33.8 Intel® ME Firmware behavior in Coffee Lake

The power management flow of consumer firmware is the same as Kaby Lake one. Table 33-7 shows the behavior of corporate firmware.

Table 33-7. Corporate Firmware behavior

Power Policy	Power flow changes in Coffee Lake
PP1 Intel® ME is on in S0 Only	Intel® ME will be ON after G3-exit, Deep Sx exit, Type 8 GRST (which is Power Button Override) and will be OFF after reaching its destined Sx State.
PP2 Intel® ME is on in Sx State	None

Refer Intel® Management Engine 12.0 Delta Doc (RDC#570744) or Intel® ME FW documents for more detail.

33.9 Schematics Design Checklists

This section provide schematics, PCB and System checklists for Intel® ME Coffee Lake design to help the design review. It should not be used as a substitute for the Design Guidelines. We recommend that customer will make the best design according the design guidelines provided, and will consult with Intel Application Engineer if there is any violation to the Intel® ME Design Guidelines.

33.9.1 Overview

Below is a checklist of items containing hardware and EC firmware requirements to support various Intel® ME technologies. If there are any questions to fill out the checklist below please work with an Intel® ME Application Engineer for assistant.



33.9.2 Intel® ME Checklists

Table 33-8. Hardware and EC firmware Requirements Checklist

Hardware Requirement	Expected Configuration	Verified (Y/N)	Issues/Next Steps
Intel® ME Requirements – All Platforms Supporting Intel® ME			
Intel® ME-EC: Intel® ME-EC connections according to the latest revision of Intel® ME-EC Interaction Specification			
Intel® ME-EC: Specific focus - SLP_S3# line between EC and PCH	Optional for platforms with M3 support. Required for platforms without M3 support. If SLP_A# is routed from PCH to EC, then SLP_S3# can be optional from Intel® ME-EC perspective.		
Intel® ME-EC: Specific focus - SLP_A# line between EC and PCH	Required for platforms with M3 support. SLP_A# should be routed from the PCH to the EC. SLP_A# asserted low informs the EC when Intel® ME is in an M-Off state. Depending on the platform, this pin may be used to control power to various devices that are part of the Intel® ME sub-system in the platform.		
Intel® ME-EC: Specific focus – ACPRESENT line between EC and PCH	Required for systems with and without M3. The ACPRESENT pin is used by EC to indicate to the Intel® ME the current power source of the system. When asserted, it indicates that the platform is connected to an AC source.		
Intel® ME-EC: Specific focus – SUSPWRDNACK/ SUSWARN# line between EC and PCH	This signal is called GPPC_A_13_SUSWARNB_SUSPWRDNACK in the PCH documentation. This pin asserts low when the PCH is planning to enter the Deep Sx power state and remove Primary power (using SLP_SUS#). The EC/motherboard controlling logic must observe edges on this pin, preparing for SUS well power loss on a falling edge and preparing for Primary well related activity (host/Intel® ME wakes and runtime events) on a rising edge. SUSACK# must be driven to match SUSWARN# once the above preparation is complete. SUSACK# should be asserted within a minimal amount of time from SUSWARN# assertion as no wake events are supported if SUSWARN# is asserted but SUSACK# is not asserted. Platforms supporting Deep Sx, but not wishing to participate in the handshake during wake and Deep Sx entry may tie SUSACK# to SUSWARN#. This pin is multiplexed with SUSPWRDNACK since it is not needed in Deep Sx supported platforms.		
SLP_SUS#	Deep Sx Indication: When asserted (driven low), this signal indicates PCH is in Deep Sx state where Primary Well is shut off for enhanced power saving. When de-asserted (driven high), this signal indicates exit from Deep Sx state and Primary Well can be applied to PCH. If Deep Sx is not supported, then this pin can be left unconnected. Note: This pin is in the DSW power well.		
SUSACK#/GPP_A15	This signal is called GPPC_A_15_SUSACKB in the PCH documentation. Active low signal is an input to the PCH (driven by the EC) and is involved in Deep Sx entry and exit flows. For more information about SUSACK#, refer to the "Cannon Lake Platform Controller Hub (PCH-H) - External Design Specification (EDS) - Volume 1 of 2" RDC#571182. For platforms that do not support DeepSx mode, this signal can be left unconnected.		



Hardware Requirement	Expected Configuration	Verified (Y/N)	Issues/Next Steps
Intel® ME Power	Intel® ME is powered by two power wells: the vccprim_core Power well and VCCSPI power supply wells. Intel® ME controls its own internal power states.		
SPI Write-Protect Pin	Must be pulled up to one of the following rails: A rail enabled by of SLP_LAN# or SLP_A#.		
SPI Flash Connectivity	SPI flash must be directly connected to the PCH if the ME FW boots from SPI.		
Timing Parameters and hardware Sequences	Customers should ensure their platform follows the timing constraints spelled out in the "Platform Power Sequencing Specification" chapter in this document.		
Manufacturing Mode Jumper (HDA_SDO/I2S0_TXD, previously known as HDA_SDO)	Flash Descriptor Security Override/Intel® ME Debug Mode If strap is sampled low, the security measures defined in the Flash Descriptor will be in effect (default) If sampled high, the Flash Descriptor Security will be overridden. This strap should only be asserted high via external pull-up to 3.3A rail in manufacturing/debug environments ONLY. Note: Asserting the HDA_SDO/I2S0_TXD high on the rising edge of PCH_PWROK will also halt the Intel® ME firmware after PCH bring up and disable runtime Intel® ME features. This enables debug mode system operation and must not be asserted after manufacturing/debug are complete.		
PCH Intel® ME XDP Debug port	Connect the PCH JTAG signals directly to PCH XDP debug port connector as described in the "Platform Debug and Test Hooks" chapter in this document.		
Intel® ME Requirements – All Platforms Supporting Intel® ME in Sx States (M3)			
Intel® ME-EC: Specific focus - SLP_A# line between EC and PCH	Required if platform supports M3, otherwise optional.		
Controller Link: Did you verify that the Controller Link design conforms to the design guidelines?	For Controller Link design guidelines, refer to Section 33.6.1.1, "Intel® ME Wireless Controller Link" .		
Intel® ME Requirements – All Platforms Supporting Intel® Active Management Technology (Intel® AMT)			
Power to LAN – hardware connections	LAN must be powered by a rail enabled by SLP_LAN#.		
Power to LAN – Behavior of hardware/ EC firmware	Power to LAN while powered must not be interrupted by either hardware or EC firmware, on any event (including warm reset, power-cycle reset).		
Power to WLAN – hardware connections	To support WLAN out-of-band in both S0 and Sx/AC states, the WLAN device must be powered by WLAN supply well" which is derived by ORing between SLP_A# being high and SUSPWRDNACK being low. To support WLAN out-of-band in S0 state only, the WLAN device must be powered by Core well that is on in S0.		
Power to WLAN - Behavior of hardware/ EC firmware	Power to WLAN, while it's powered due to previous item, must not be interrupted by either hardware or EC firmware, on any event (including warm reset, power-cycle reset).		



Hardware Requirement	Expected Configuration	Verified (Y/N)	Issues/Next Steps
Implement one of the 2 proposed 18-pin Intel® APS connectors	Customers are expected to follow the PDG and implement one of the two Intel® APS connectors recommended in the Section 33.7, "Intel® APS" .		
Was CLink layout designed to conform to design guidelines	Customers are expected to follow the PDG and design the CLink according to Section 33.6.1.1, "Intel® ME Wireless Controller Link"		

§ §



34 Intel® Integrated Sensor Solution

34.1 Acronyms

Acronyms	Description
AE	Application Engineer
AIO	All In One
ALS	Ambient Light Sensor
AVL	Approved Vendor List
BOM	Bill Of Material
CFL	Coffee Lake
EC	Embedded Controller
FDK	Firmware Development Kit
FW	Firmware
GPIO	General Purpose Input/Output
I ² C	IIC - Inter-Integrated Circuit bus
IISS	Intel® Integrated Sensor Solution
Intel® ISH	Intel® Integrated Sensors Hub
Intel® ME, ME	Intel® Management Engine
OxM	ODM or OEM
pAIO	personal All In One
PCB	Printed Circuit Board
POR	Plan Of Record
SAR	Specific Absorption Rate
SUT	System Under Test
uDriver	Micro Driver
ZIF	Zero Insertion Force (connector)

34.2 Reference Documents

Document	Document Number
Ultrabook™ Platform - Magnetometer Design Integration - Technical White Paper	RDC#535305
Cannon Lake PCH-H External Design Specification - Volume 1 of 2	RDC#571182
Cannon Lake PCH-LP External Design Specification - Volume 2 of 2	RDC#565870
Intel® Integrated Sensor Solution (IISS) POR BOM	RDC#570092
Integrating Motion and Orientation Sensors (by Microsoft*)	https://msdn.microsoft.com/en-us/library/windows/hardware/dn642102(v=vs.85).aspx

34.3

Introduction

Coffee Lake Platform uses an Intel® Integrated Sensor Hub (Intel® ISH), bearing the name "Coffee Lake Intel® Integrated Sensor Solution" (Coffee Lake IISS). This section provide the implementation recommendations for the Intel® Sensor Solution for 2-in-1 (Detachable), 360 clamshell, pAIO (personal All In One) and AIO (All In One) systems design. The intent of this document is to assist the usage of Coffee Lake IISS and sensor devices in hardware design to meet the Microsoft Windows* 10 Operating Systems sensor recommendations.

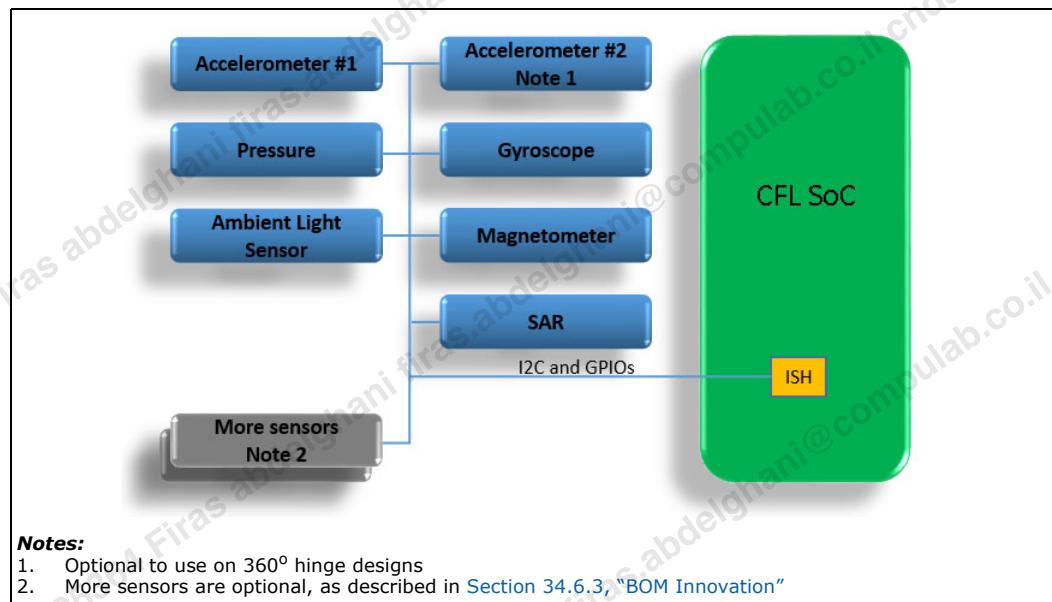
It is highly recommended to follow all of the design guidelines and perform all checklists and to not deviate from any of the recommendations outlined in this document to prevent or minimize any functionality or responsiveness risks.

34.4

Overview

Coffee Lake IISS is to be used on the Coffee Lake platform with Windows 10* Operating Systems (OS) with the combination of sensors, Integrated sensor hub and Intel® sensor firmware and software. [Figure 34-1](#) shows the sensor solution block diagram including the interconnection between Coffee Lake processor and the sensors.

Figure 34-1. Intel® Coffee Lake IISS Diagram



Also, refer to [Section 34.7.1.1](#) and [Section 34.7.1.2](#) for example of actually connecting Sensors to the SoC.

34.5

Sensors

Intel defined a list of sensors, hereinafter defined as BOM, to support customers with different needs. Intel fully supports sensors defined in the BOM, did full validation cycle on them and now supports it as a turn-key solution.



IISS firmware algorithms support only unprocessed and unfiltered raw data, coming directly from the sensors. The use of firmware with the built-in processor that is available on some sensor devices to pre-process the sensor data is not supported by Intel® ISS Firmware.

In previous IISS generations, it was proposed to use a second magnetometer to be located on the base of a 360 degrees hinge swivel designs, used to detect if the lid was facing up/down. However, this option was eliminated and customers requested to use a simple Hall effect sensor. This Hall Effect solution is now Intel's POR, instead of the second magnetometer.

Table 34-1. Sensor Types and Supported Form Factors

Device	Type	2-in-1	Clamshell
3-Axis Sensors	Accelerometer	POR	POR
3-Axis Sensors	Magnetometer	POR	POR
3-Axis Sensors	Gyroscope	POR	POR
6-Axis Sensors	Accelerometer + Magnetometer	POR	POR
6-Axis Sensors	Accelerometer + Gyroscope	POR	POR
9-Axis Sensors	Accelerometer + Gyroscope + Magnetometer	POR	POR
Ambient Light Sensor	Ambient Light Sensor	POR	POR
Pressure	Pressure	POR	POR
SAR Sensor	Specific Absorption Rate sensor	POR	POR

Notes:

1. IISS firmware algorithms support only unprocessed and unfiltered RAW data, coming directly from the sensors. The use of built-in firmware for the built-in processor that is available on some sensor devices to pre-process the sensor data is not supported by IISS Firmware.
2. However, it is on their own discretion to provide the full chain of components such as the uDriver, validate and resolve all issues in house, as sensor not in the BOM list were not validated by Intel.

34.6

Sensors Extensibility Options

One of the most important IISS program objectives is Sensor Extensibility. It refers to the ability for the customer to change the sensor - the flexibility to choose different vendor for the sensor types that are included in the proposed Intel BOM or the option to innovate by selecting a totally new sensor type. Intel has developed the IISS Firmware Development Kit (FDK) to enable the extensibility. Please contact your local IISS AE for a FDK release. Following are the implementation highlights:

34.6.1

Baseline

- Sensors BOM can be found in "Intel® Integrated Sensor Solution (IISS) POR BOM".
- Basic: Windows* HCK support.
- Intel differentiated: pressure sensor.
- Advanced algorithms: activity context, device context and gesture.
- Support: Full support (Fully validated on Intel systems, with Intel supported BOM).



34.6.2 BOM Flexibility

- Feature Set: Intel baseline.
- BOM: OxMs can choose to replace sensor vendor for supported sensor types.
- Support: Intel provides FW and FDK, OxM integrates customer uDriver.
- uDriver: OxM owns FW integration, calibration, and validation.
- Intel will provide a FDK development toolkit for OxM use.

34.6.3 BOM Innovation

- Feature Set: Not validated, but Intel base-line functionality supported.
- BOM: OxMs can choose to add new types of sensors and/or algorithms.
- Support: Intel provides FW and FDK, OxM integrates custom uDriver and algorithms.
- uDriver: OxM owns FW integration, calibration, and validation.

Note:

Based on the definitions above, customer may choose any sensor from the market. It is important to be noted that sensors are characterize also by the voltage they use for the I²C interface and interrupts (defined as V_{io}), which may be either 1.8V or 3.3V. This means that the Intel® ISH, the sensors and the pull-up resistors all should use the same V_{io} voltage, either 1.8V or 3.3V. If customer's BOM calls for use of sensors which do not support the same V_{io} voltage, customer should use a voltage level shifter where appropriate.

34.7 Design Integration

Intel highly recommends thoroughly understanding and implementing all of the design requirements outlined in the device data sheet, and following all the requirements specified in this chapter for design integration. Failure to do so may result in sensor malfunctioning and support problem.

The physical locations of the sensors on the motherboard or daughter board, or in the system depend on board placement, system placement, and the form factor. Intel firmware has the flexibility to accommodate for orientation of 0°, 90°, 180° and 270° with reference to the recommended orientation in the followed subsections. It's required that the edges of the sensor with directivity or used for fusion are in parallel with the system edge, and they must be placed in a fixed orientation relative to each other. It is recommended to place them on the same board. Selection of individual sensors is based on the operating system requirements and usage models planned for the system.

34.7.1 Electrical Design

All manufacturers' data sheets and application notes need to be followed. It is recommended to include signal or function description, trace length and air gap information in schematics where ever possible. Refer to the data sheets for the pin definitions and the reference schematics for the detail interconnections.



34.7.1.1 Sensors - I²C Bus Considerations

The sensors may be connected to Intel® ISH through Intel® ISH I²C interface and Intel® ISH GPIO. Sensors can be connected to ISH_I2C0 or ISH_I2C1, but it is recommended not to use ISH_I2C2 as it may be used for other functions.

I²C interface is used for data transmission. It is important to note that Intel® ISH I²C interfaces support I/O voltage with either 1.8V or 3.3V voltage, and sensors are characterized also by the voltage they use. If customer's BOM calls for use of sensors which do not support the same voltage, customer should use a voltage level shifter where appropriate. It is recommended, however, to use sensors which support the same I/O voltage. The I²C interface may run at speeds up to 1Mbps and due to the relatively low speed there are few signal integrity issues to worry about. It is required to ensure the total loading does not exceed the maximum bus capacitive load. There is no specified location for ISH_I2C pull-up resistors, but it is recommended to place the pull-up resistors on motherboard if sensors are on daughter board.

Connecting I²C debug device that has build in I²C pull-up resistors will change the final value of pull-up resistors, and the wrong pull-up resistors can cause Intel® ISH I²C bus not to work. Refer [Chapter 23, "I²C* Interface Design Guidelines"](#) in this Design Guide.

Refer to the sensor data sheets for selecting the correct power voltage (3.3V or 1.8V) for the sensor components. For the component that have a separated I/O power supply, please select the corresponding voltage (V_{IO}) level according to the voltage level of I²C bus. For 1.8V I²C, an 1.8V I/O power supply is needed. For 3.3V I²C, a 3.3V I/O power supply is needed.

Note:

Please be noticed on your early designs. It is strongly recommended to reserve pads of series resistor and stuff with 0 Ohm resistors on Intel® ISH I²C clock and Intel® ISH I²C data lines. Designers could separate sensor components onto ISH_I2C0 and ISH_I2C1. By doing this, it can keep flexibility of circuits if an adjustment is needed on your PCB.

34.7.1.2 Sensors - GPIO Considerations

For sensor interrupt, the Intel® ISH GPIO pin is configured as an input and connect to the interrupt output of a sensor. **Intel strong recommend that sensor components should not share one or more interrupt line(s). Intel® ISH FW does not support it.**

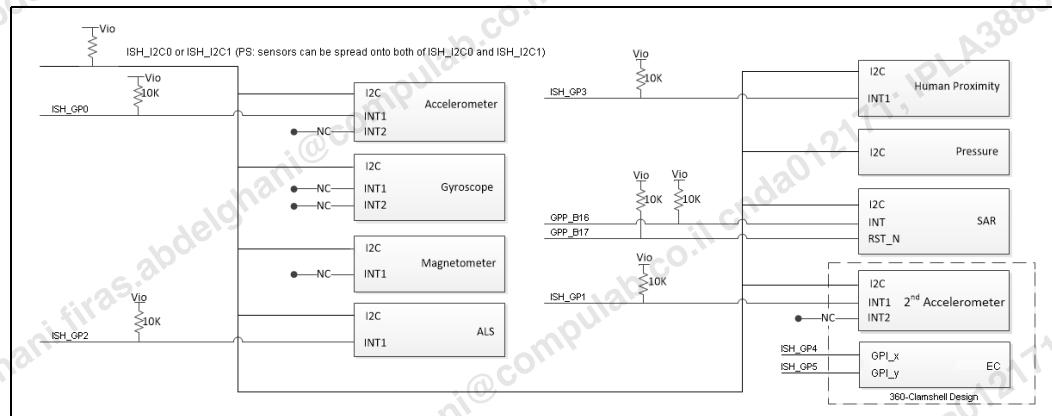
For Lid-close sensor (as-known-as hall sensor), it is strongly recommended to add an additional route of Lid-close interrupt output to the Intel® ISH GPIO if the Lid-close sensor interrupt is already connected to EC. It is must in a 360-degree clamshell design. By doing this, it can help Intel® ISH FW to distinguish and calculate the correct angle between the lid and the base. For example, the angle of 0 and 360 degrees in a 360-clamshell design.

For a 360-degree clamshell design which needs a 2nd accelerometer on the base, and other sensors are on th lid. In this case, some of Intel® ISH GPIO pins are configured as output. With Intel® ISH virtual sensor support, Intel® ISH FW can trigger outputs to EC via these GPIO pins. One pin can represent two modes, two pins can represent four modes and so on. Usually two pins are enough. For example, if we divide the angel between the lid and the base into 4 regions, 0~5 degrees means lid close, 355~360 degrees means tablet mode, 15~185 means clamshell mode, 195~345 means book mode. Two GPIO pins can represent 4 modes and so on. The EC can read these two pins to know which mode it is now. Based on this information, The EC can control on/off

to keyboard, touchpad and more.

Figure 34-2 is an example of I²C bus and interrupt connection. All interrupts should have its own pull-up resistors for supporting Open Drain configuration in Intel® ISH FW. Please also refer the sensor vendor datasheet for the corresponding interrupt connections.

Figure 34-2. An example of ISH_I2C and ISH_GP connection



As can be seen in **Figure 34-2**, interrupt connections of Gyroscope, Magnetometer, Human Proximity and Barometer sensors to the Intel® ISH are not required although the sensors offer this capability. The Intel Basic BOM uDrivers are not utilizing these interrupt requests from these sensors. If designer wishes to use interrupts from these sensors, a new sensor uDriver is needed to be developed to each sensor with IISS FDK.

34.7.1.3 Sensors - Configurable Voltage Considerations

Refer to "Cannon Lake Platform Controller Hub (PCH-H) - External Design Specification (EDS) - Volume 1 of 2", RDC#571182, section 17.4.1. Except Group F and GDD, configurable voltage selection per pad is supported in most of GPIO groups since CNP (which is CNL PCH). The configuration is done via soft straps during booting. Before soft straps are loaded, the default voltage of each pin depends on its default as input or output.

- Input: 1.8V level with 3.3V tolerant.
- Output: the pin drives 3.3V via a ~20K pull-up. With this, any 1.8V device must be capable of taking 20K pull-up to 3.3V.

Warning: GPIO pad voltage configuration must be set correctly depending on device connected to it; otherwise, damage to the PCH or the device may occur.



34.7.2 Layout and Assembly

All manufacturers' datasheet, application notes and design recommendations for mechanical placement, soldering and assembly must be followed. **For the combo parts that have more than one sensor in it, the guidances for all the built-in sensors need be followed.**

The general rules:

- **Please make the sensor placement to be the first step when outlining a new PCB layout. Plan accordingly accommodating to both of board and system level.**
- Please understand and follow all the layout and design rule requirements from the sensor vendors and manufacturers.
- Please place sensor 2 or 3 cm away from hot devices to avoid large temperature gradient.
- Please place sensors at interference-free locations on the board in the system for all usage models.
 - Place motion sensors in a stable position and isolated from any vibration.
 - Place magnetometer away from magnetic interference.
 - Place the ambient light sensor away from any unwanted lighting sources (for example: a LED indicator) in the system. Also make sure that the ambient light is not blocked.
- Please Do NOT place the sensor in a region of PCB that can warp as it can cause package stress which causes shift.
- Please Do NOT place the sensor at the position which has unsymmetrical stress coming from PCB deformation as it will cause drift.
- Please design for manufacturing: Design a system that the board is easy to be assembled in and ensure the board is fixed firmly and there is no flex after the assembly.
- It is strongly recommended on the top metal layer, the area just below the sensor component, not to place any metal structure such as via, trace, plane and etc., meaning no metal entity under the sensor component on the PCB.

34.7.3 Form Factor Considerations

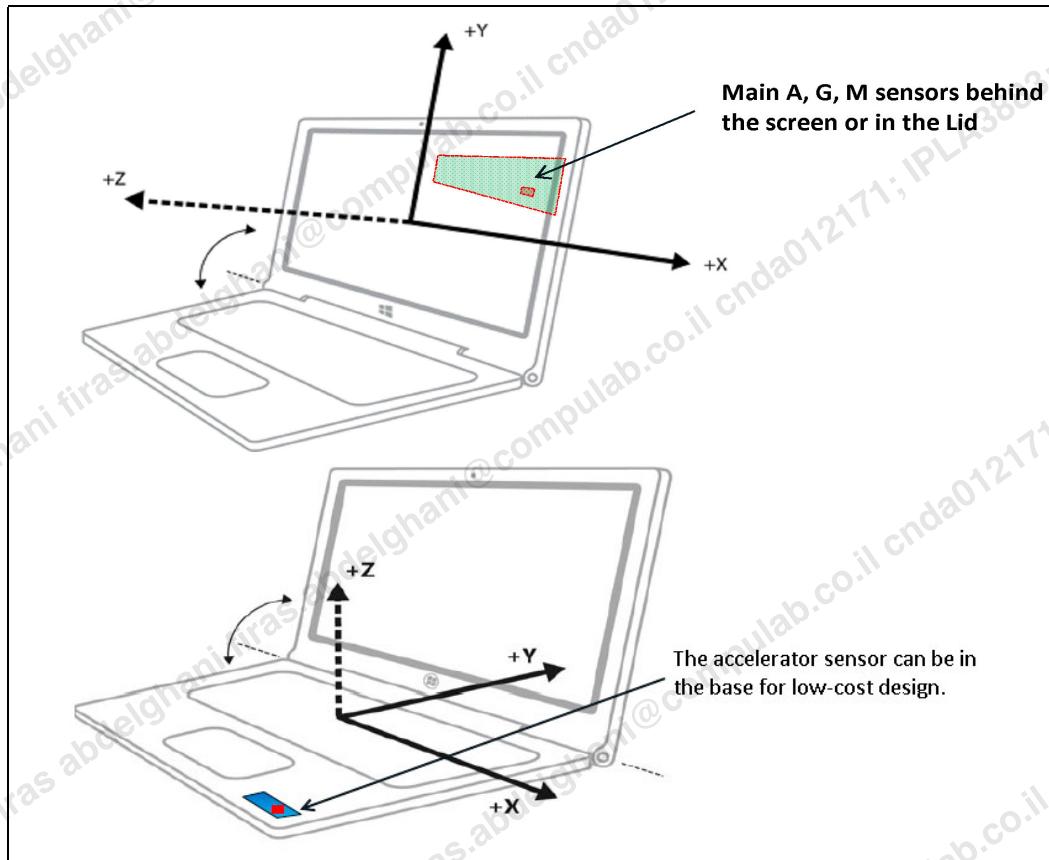
This section illustrates the sensor placement for form factors such as Ultrabook™ 2-in-1 (Slider, Twist, Ferris Wheel, 360 hinge, dual Screen, etc.), Ultrabook Detachable, Ultrabook Clamshell and pAIO (portable All In One).

For all the form factors, it is recommended to place the main motion sensors behind screen or in the LID, and place the 2nd accelerometer for 360-Hinge design in the base.

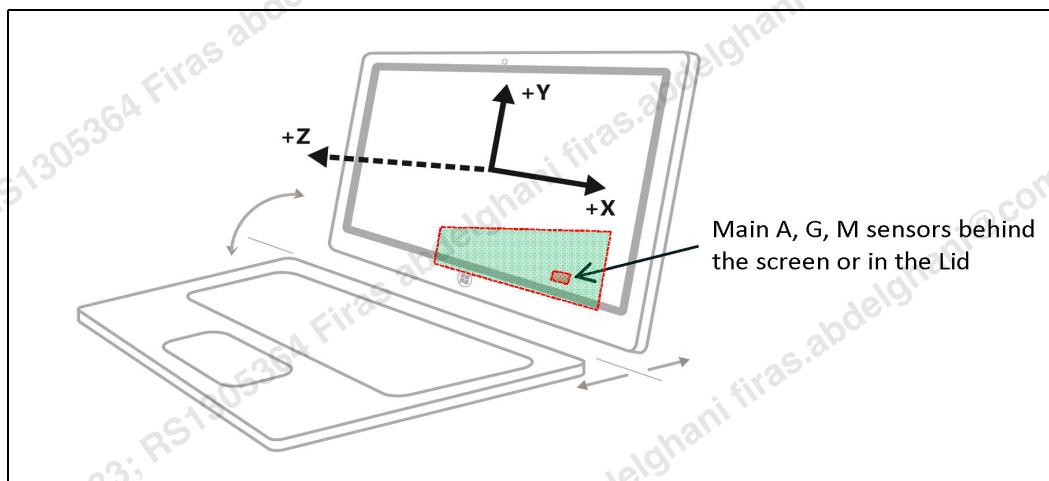
For low-cost clamshell design which only supports screen rotation, the accelerometer sensor can be placed in the base.

System/Chassis Integration Options:

- Clamshell: Main sensors behind the screen or in the Lid. For low-cost design, the accelerator sensor can be in the base.

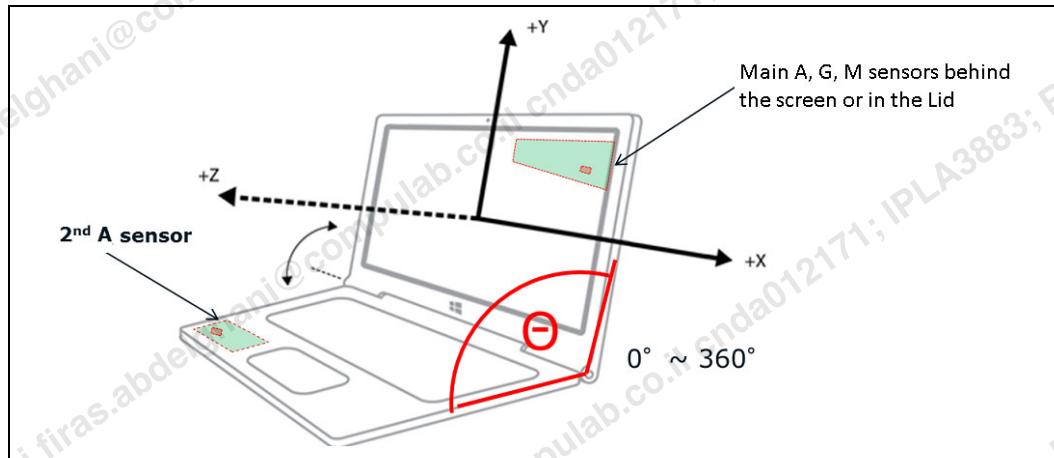
Figure 34-3. System/Chassis Integration Options: Clamshell

- Detachable: Main sensors behind the screen or in the Lid.

Figure 34-4. System/Chassis Integration Options: Detachable

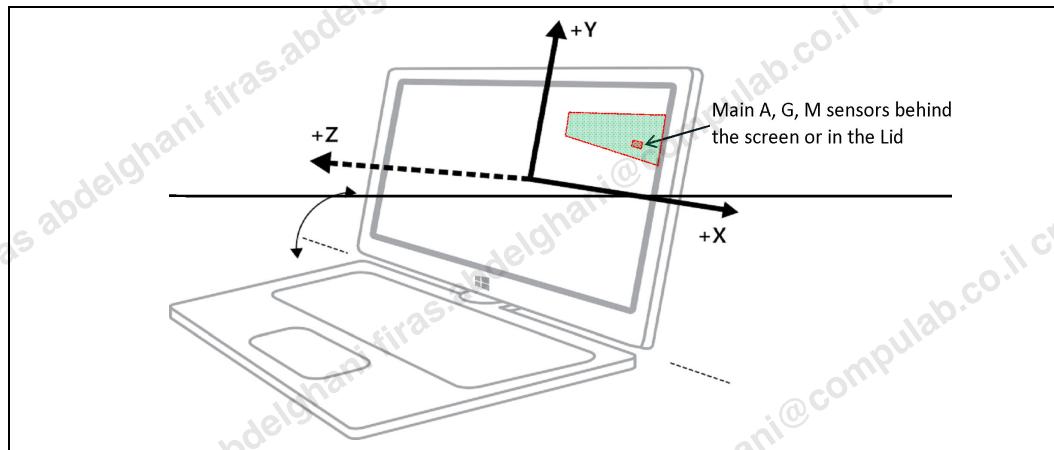
- 2-in-1 with 360 hinge: Main sensors behind the screen (LID) while the 2nd sensor in base.

Figure 34-5. System/Chassis Integration Options: 2-in-1 with 360 Hinge



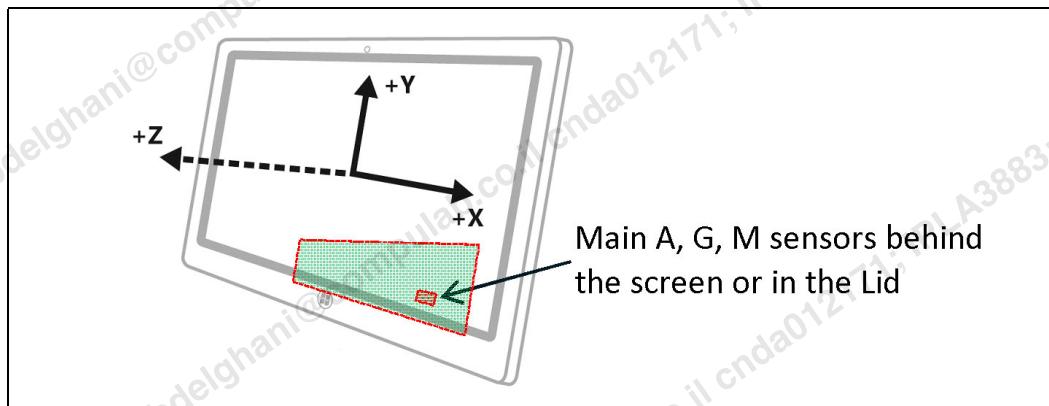
- Other 2-in-1: Main sensors behind the screen (LID) or in the LID.

Figure 34-6. Other 2-in-1: Main A, G, M sensors behind the screen or in the Lid



- pAOI: Main sensors behind the screen (LID)

Figure 34-7. System/Chassis Integration Options: pAOI



34.7.3.1 Ambient Light Sensor (ALS)

The ALS must be placed in the lid as close as possible to the camera module (if present), in order to allow effective control of screen brightness based on ambient light. The performance of the display brightening is ultimately defined by the performance of ambient light sensor and dimming to specified LCD luminance levels in response to lighting changes. While the firmware has the ability to control the ALS signal gain and the LCD luminance response, proper mechanical design is still required to ensure the right user experience. Several hardware features must be considered when integrating ambient light sensors into PCs.

- **ALS Characteristics:**

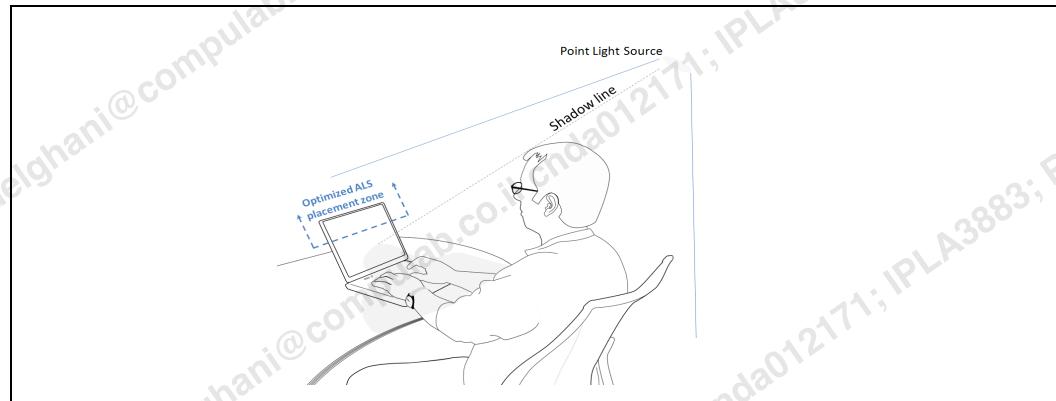
Table 34-2. ALS Characteristics

Characteristic	Specification	Notes
Illuminance Range	5-100k lux	As output through sensor module which includes optics, surfaces, calibration data and etc. It's not only related to the bare sensor.
Accuracy	+/- 10%	As output through sensor module which includes optics, surfaces, calibration data and etc. It's not only related to the bare sensor.
Type	Digital	16-bit resolution
ALS IR/UV rejection	Supported	Important for consistent measurement

- **Aperture Placement:**

The light sensor aperture is required to be located on the same plane as the display which is facing the user. This is necessary because the sensor measures the lighting conditions facing the user for supporting adaptive brightness and light-aware applications that display their content on the screen.

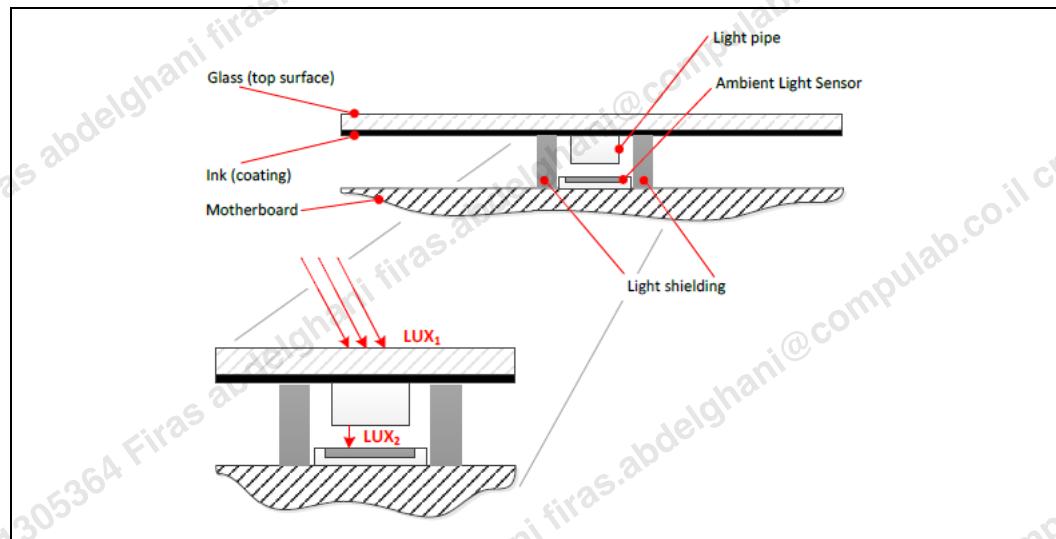
- Please avoid placing the light sensor in areas of the computer that are likely to be obscured from the light source or sources by shadows.
- **Figure 34-8** illustrates an example of user scenario in which a direct light source is behind the user. A shadow is cast over the lower half of the screen and the base of the computer. This scenario suggests that the optimal light sensor placement is near the top of the screen and facing the user.

Figure 34-8. Ambient Light Sensor Cross Section

- **Aperture Size:**

The aperture must be wide enough to detect light without significant attenuation when the light source is at an angle to the device or from a diffused source. A hole too small or too deep could cause a "Shadow Effect" which reduces the usability of the ALS sensor.

OEM should work with their sensor manufacturer to determine the minimal and optimal aperture size.

Figure 34-9. Ambient Light Sensor Cross Section

- **Optical filter:**

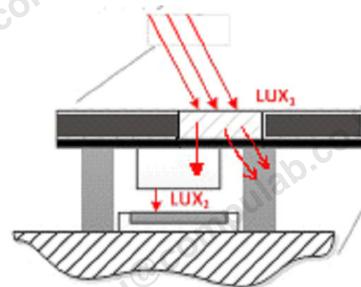
In some instances, an optical film or ink coating may be applied to hide the ALS optical cavity. **The filter must be designed to allow at least 80% of visible wavelength light to pass.** That is, a light meter placed behind the film must register at least 80% of the LUX value from a direct light source that it registers with the film removed.

- **Light pipe:**

A light pipe constructed from a light-conducting material may optionally be deployed to increase the light-gathering ability of the optical cavity. This may be required in cases where the ALS optical cavity is excessively deep, inhibiting light gathering from off-axis (i.e., angled) and diffused light sources.

- **Cover Consistency of Glass/Cover:**

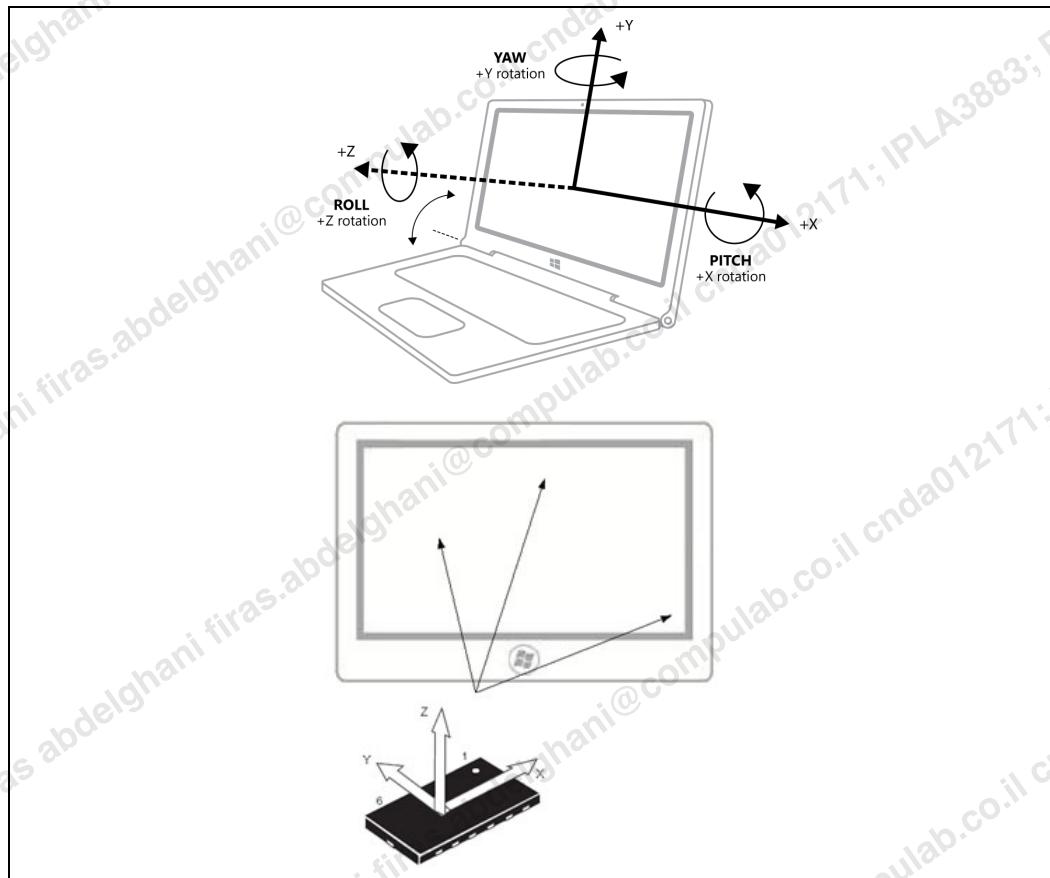
- The glass or plastic covering material must be consistent across the units of the same SKU/Model. Failure to follow this recommendation will result in inaccurate readings from the ALS based on the per Model-Calibration parameters.
- Care must be taken when placing the Glass/Cover; a misalignment would mask out some of the light and produce unexpected readings from the ALS.



34.7.3.2 Gyroscope

- The X, Y and Z axes of the sensor chip orientation is recommended to match the diagram below.

Figure 34-10.Gyroscope X, Y and Z Orientation

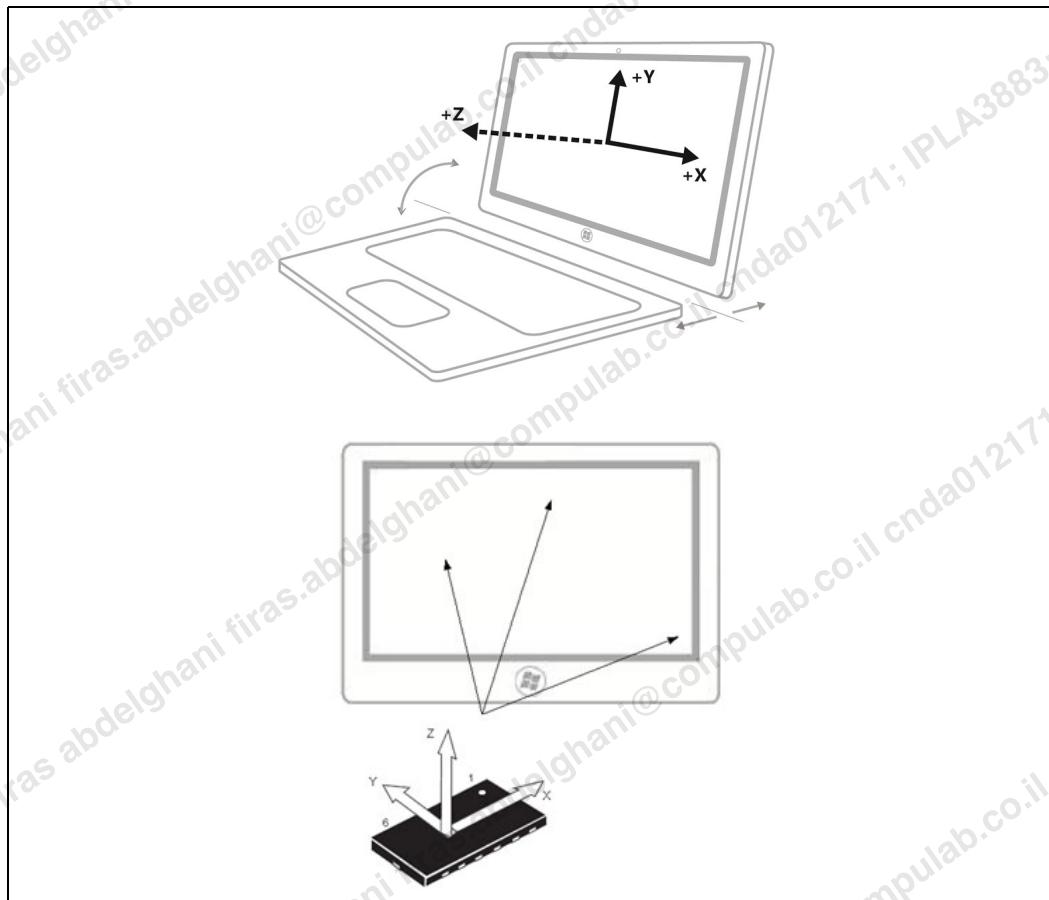


- Gyroscope must be mounted securely, near a screwed standoff point, and can not move independently.
- Gyroscope must be placed in a stable position and isolated from any vibration including transmitted vibration, air pressure change vibration and etc.
- It is recommended that gyroscope is kept a distance of 30 mm from audio speakers, fans and haptic vibration motors.

34.7.3.3 Accelerometer

- The X, Y and Z axes of the sensor chip orientation is recommended to match the diagram below.

Figure 34-11. Accelerometer X, Y and Z Orientation

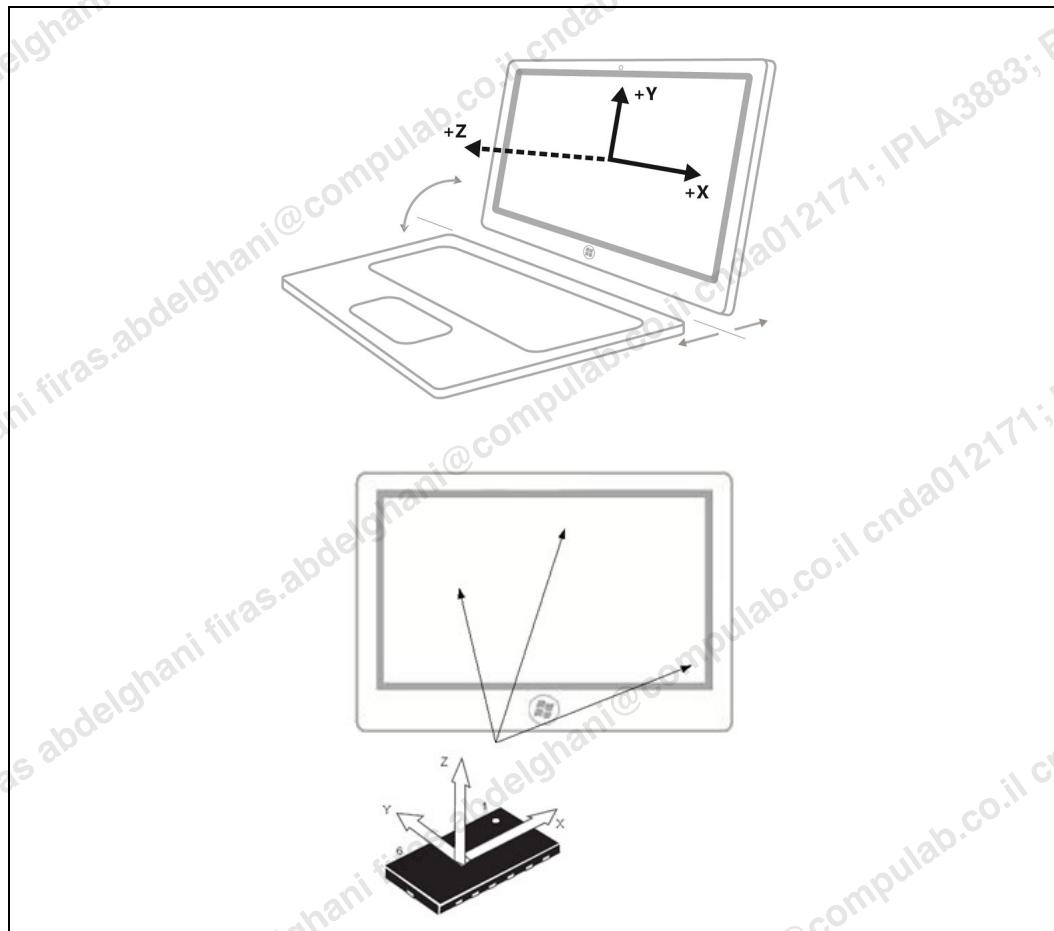


- Accelerometer must be mounted securely, near a screwed standoff point and can not move independently.
- Accelerometer must be placed in a stable position and isolated from any vibration including transmitted vibration, air pressure change vibration and etc. It is recommended that accelerometer is kept a distance of 30 mm from audio speakers, fans, and haptic vibration motors.
- Many modern electronic accelerometers have the ability to perform on-board filtering e.g., the purpose of removing DC gravity components in the signal. All accelerometer signal conditioning and signal thresholding are performed within the integrated sensor hub firmware.

34.7.3.4 Magnetometer

- The X, Y and Z axes of the sensor chip orientation is recommended to match the diagram below.

Figure 34-12. Magnetometer X Y and Z Orientation



- Please make the magnetometer placement the first step when outlining a new PCB layout.** The ideal location for the magnetometer is to be as far away as possible from magnetized components, high current components or traces. The best locations are often to be found on an edge or at a corner of the PCB.
- Please must be placed at least 40 mm from any rare earth magnets (speaker magnets, LID magnets, etc.), and inductors.
- Please must be placed at least 30 mm from any large/thick (structural) ferrous metals, the components which includes the magnet of a hard disk, digitizer, the components with the magnetism of 100 Gauss.
- Please keep a minimum distance of 10 mm from the components which include microphone, vibration motor, magnetic switch, transformer, camera module, beeper, battery, SAW filter, antenna, power amplifier, choke, LCD rear case and the components with the magnetism of 5 Gauss.
- Please keep a minimum distance of 5 mm from the components which include Memory/SIM card socket, USB connector, other connectors, screw, nut, spring, EMI



shielding part, the components with the magnet-conductive material (Iron, Cobalt, Nickel).

- 2 mm away from the surrounding resistor and capacitor since nickel plating is usually present on solder end caps of surface mount components.
- **Please keep away from the power trace (including power or ground plane) on all the PCB layers or component on both PCB sides or out of the board with the variable current higher than 10 mA. For instance: keep a minimum distance of 20 mm from the trace that carries the variable current of 100 mA or keep a minimum distance of 25 mm from the trace that carries the variable current of 200 mA.**
- **Constant current has the interference as magnet. The magnet field created by it is found using the following equation. Please make sure the interference does not cause the output of the magnetometer over the measurement range of the magnetometer.**

$$B = \frac{m_0 * I * L}{2\pi R \sqrt{(L^2 + 4R^2)}}$$

B = magnetic field strength in Teslas

m_0 = permittivity of free space ($4\pi * 10^{-7}$ T*m/A)

I = current in Amps

L = Conductor length in Meters

R = Radius in Meters

- Please Do NOT cover the magnetic sensor with any material that can block the static magnetic field from magnet and earth.
- As far as possible from mechanical based HDDs, vibrators, hearing aid coils and battery connector which contain ferromagnetism, high frequency circuits and power circuits.
- Please make sure LCD back shell, shield (for RF, BT...) and mechanical part (key, screw, connector) do not contain ferromagnetism material (Fe, Co, Ni).
- The same rules apply to the opposite side of the board.
- The same rules apply to any daughter boards or other components sandwiched in proximity to the magnetometer.
- Please make sure the rules are followed in all the usage models. (Example: with magnetometer in the lid, consider components on the base in tablet mode.)

Note:

For the means to calculate the possible interference, refer to Magnetometer Design Integration Challenges - White Paper, RDC#535305.

All digitizer solutions that employ a ferrous-based shield are unsuited for deployment with the magnetometer. Digitizers that require a ferrous-based shield are not supported by Intel due to the excessive soft iron distortion induced on the e-Compass. Other platforms possessing digitizer solutions that do not require a ferrous-based shield must conform to the general platform guidance for deploying magnetometer.



34.7.3.5 Pressure Sensor

In order to achieve the specified performance for your design, the following recommendations when mounting a pressure sensor on a printed-circuit board (PCB):

- The clearance above the sensor package shall be 0.1mm at minimum.
- For the device housing appropriate venting needs to be provided in case the ambient pressure shall be measured.
- Liquids shall not come into direct contact with the device.
- During operation Pressure sensor is sensitive to air pressure variation, fast heating and light heating which can influence the accuracy of the measurement.
- The pressure sensor should not be placed at the position where has unwanted fast air pressure variation caused by fans, speaker etc.
- The pressure sensor shall not be placed close the fast heating parts in case of gradients $> 3^{\circ}\text{C/sec}$. it is recommended to follow the vendor's application note and contact the vendor representative for details.
- The area below the sensor (on the same side of the board) must be defined as keep-out area. It is strongly recommended not to place any structure in top metal layer underneath the sensor.

34.7.3.6 SAR (Specific Absorption Rate) Sensor

SAR sensor is used as a proximity sensor to identify conductive objects (human body parts such as ear, head, lap and torso) presence near the transmitting system antenna. The purpose of the SAR sensor is to allow a device to transmit at higher powers when not located in close proximity to a body and operate at lower powers when close to the body. Many regulatory bodies globally are aligning to International RF exposure guidelines or the FCC limits, as defined below. Examples are when the user brings the transmitting system close to his head (mobile phone) or when the system is used on the person's lap.

Relevant systems are those mobile systems that use wireless communication (transmission) of voice and/or data, including wearables, mobile phones, tablets, phablets, ultrabooks, laptops, some personal AIO (All In One) systems and more.

SAR needs to be evaluated for transmitters operating anywhere in the RF spectrum (9KHz - 300GHz) and so it is relevant to cellular technologies, Wireless LAN technologies and many other wireless technologies supporting data and/or voice.

SAR requirements limit the levels of transmitted RF power to ensure that the power absorbed by a human body is below certain limits established by regulatory bodies around the world. This may require that a device reduce its RF transmitting power when it is in close proximity to the human body. In these systems, the SAR sensor activation is used to allow the device to operate at a higher power (and increased operating range) when the antennas are not close to a body but then reduce the transmission power of the relevant antenna to ensure compliance with the RF exposure requirements.

Transmission power control was simple when there was WWAN (3G/4G/LTE) modem only, SAR output was connected directly to the WWAN modem, directly controlling the Cellular transmitter. The problem started when smart phone with IP phone emerged, so now there may be a need to control the output power from both WWAN and Wi-Fi. Co-SAR section below describes it.

Regulation Sources

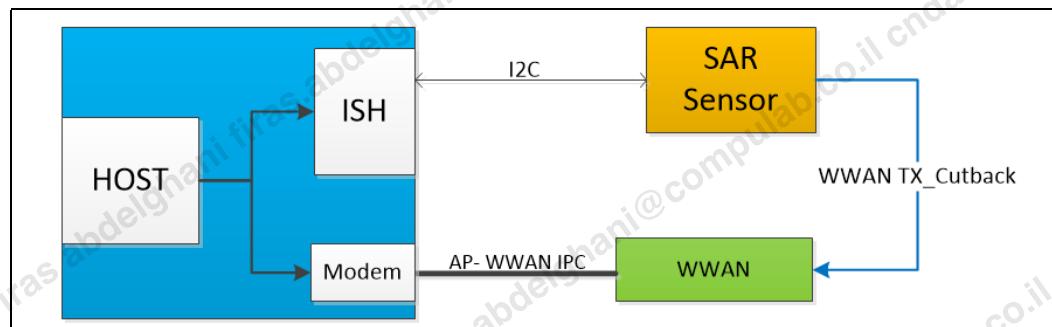
The following are the 2 RF exposure requirements for devices that are used in close proximity to the body (within 20cm). As this can be a changing field, the data published in this section is as it was known in the time of publishing of this document:

- **United States:** The relevant [FCC requirements](#) for the FCC requires that devices used in close proximity to the body have a SAR level below 1.6 watts per kilogram (W/kg) measured over the volume containing a mass of 1 gram of tissue that is absorbing the RF energy.
- **European Union:** CENELEC specify SAR limits within the EU, following IEC standards ([IEC 62209-2:2010](#)). For devices used in close proximity to the body, the SAR limit is 2.0 W/kg measured over the volume containing a mass of 10 grams of tissue that is absorbing the RF energy.

Co-SAR

A simple SAR sensor control over Antenna power is described in [Figure 34-13](#). In this way, the SAR sensor directly controls the WWAN transmitter power. This is the most efficient way remain compliant with the RF exposure requirements without any additional logic.

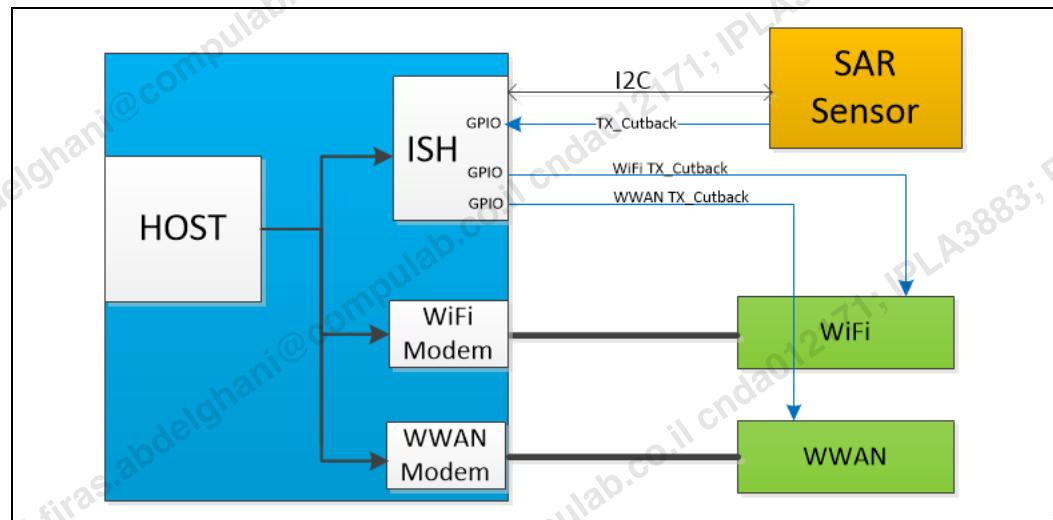
Figure 34-13.Simple SAR Sensor Control over WWAN Antenna Power



In more sophisticated systems, where system support both WWAN phone and IP phone (Such as WWAN and Wi-Fi).

[Figure 34-14](#) shows a recommended way to control antenna power using an algorithm that runs on the Operating system (OS). In this way the OS has control over each antenna, to control the transmitted power, to ensure compliance with RF exposure requirements.

Figure 34-14. Co-SAR Sensor Control over WWAN Antenna and Wi-Fi Antenna Power



Design Guidelines

There are 2 main relevant usage models that should be covered by SAR sensors, used to reduce antenna transmission power:

- When bringing the system to the users' ear, so phone speaker (and RF antennas) is closed to the users' ear and head. This is mainly relevant to "Mobile Phone" systems, such as handsets and phablets.
 - When placing the system on or close to other human body parts, such as the lap or torso. This is mainly relevant to laptop/clamshell, tablets, phablets and similar types of devices.
1. The sensor electrode may be a simple copper area on a PCB or FPC (Flexible PCB) for example with an adjacent reference ground area. Sensor electrode capacitance (to ground) will vary when a conductive object is moving in its proximity.
 2. The sensor electrode needs to be located close to the antenna, or antennas, that it is controlling. Having the sensor be away from the antenna makes trigger distances unreliable. The size, shape and position of the sensor electrode are largely dependent on the system usage model. Typically, the sensing area (position) for on ear detection is around the speaker, at the top of the (for example) mobile phone, near the camera etc.
 3. Conductive tape (copper tape) works well for prototypes, while FPC is suggested for mass production.
 4. Keep the SAR sensor area away from area that human finger touches, such as a touch screen, systems' buttons, keyboard etc. There is no need to throttle antenna power in such a case as the extremity SAR requirements are 2.0 W/kg over 10g of tissue mass.
 5. Robust electrode design is the one that minimizes environmental (parasitic) capacitance noise value and variation of it.
 6. Power reduction values need to consider both the stand-alone use of a transmitting antenna and simultaneous transmissions from multiple antennas, where supported. The combined SAR value from these antennas needs to meet the relevant limits.
 7. System design considerations need to ensure that the default power state is always the reduced power state such that if the SAR proximity sensor circuitry is failed.



8. The software controls need to be robust and must not be user accessible (i.e. the user must not be able to modify the power reduction settings or disable the sensor). Firmware and software updates need to be carefully tested to ensure that the proximity sensor functions are not bypassed.
9. Where the proximity sensor enables large power reduction regulatory bodies such as the FCC may expect to see a description of how the sensor performance is verified across production units. This may necessitate the use of test software and test fixtures and sampling at the production floor. Large power reduction values can trigger device surveillance testing by regulatory agencies so quality control at the production level is important.
10. In general, wherever possible, place the transmitting antennas in areas not accessible to human body parts, so eliminate the need for SAR sensor circuits and the need to lower transmission power. This is difficult in tablets, 2-in-1 and phones which are small and difficult to have an antenna that would not be in close proximity. For tablets it makes sense to keep the antennas toward the front (screen side) of the device to maximize separation from person. Other items to suggest here might be the ability to keep antennas that might operate simultaneous (Wi-Fi and WWAN in hot spot mode, for example) as far apart as possible to reduce the need for power reduction in those modes.

Device Requirements

The device selection, electrode and circuit design need to meet the following minimum requirements:

1. The sensor electrode needs to be placed on the inner side of the back cover, close to the transmission antenna, and properly shielded with ground to minimize the interference from the surrounding electronics. The shield needs to be tied to the platform ground to remove the ground bouncing noise and false proximity detection from the platform ground traces.
2. Sensor should be placed very close to the electrode to reduce noise. Routing from sensor electrode to sensor needs to be co-ax cable with ground shielding.
3. Sensor proximity range requirement needs to be determined after SAR testing, but can start with 10mm from the back and side close to where the transmission antennae are placed in the form factor system.
4. Sensor detect range should be 0-60pF with distance of 20mm from a human body part.
5. SAR sensor circuit power needs to be less than 0.1 mW.
6. SAR sensor proximity range for human body and other non-conductive material (such as tablet top) should have big enough delta so that it can be programmed/tuned to detect only the human body proximity and not other non-conductive material.

34.7.4 PCB and Cable Routing

For the I²C, and other signals routing between Intel® ISH and the sensors, refer to the corresponding sections in the PDG. **Please do not route the cables that have power wire close to the magnetometer.** For other partitions, please follow the manufacturers' requirements.



34.7.4.1 Soldering Recommendations

For soldering guidelines refer to the corresponding documents from the sensor vendors or consult the sensor vendor.

34.7.5 Sensor Problem Areas

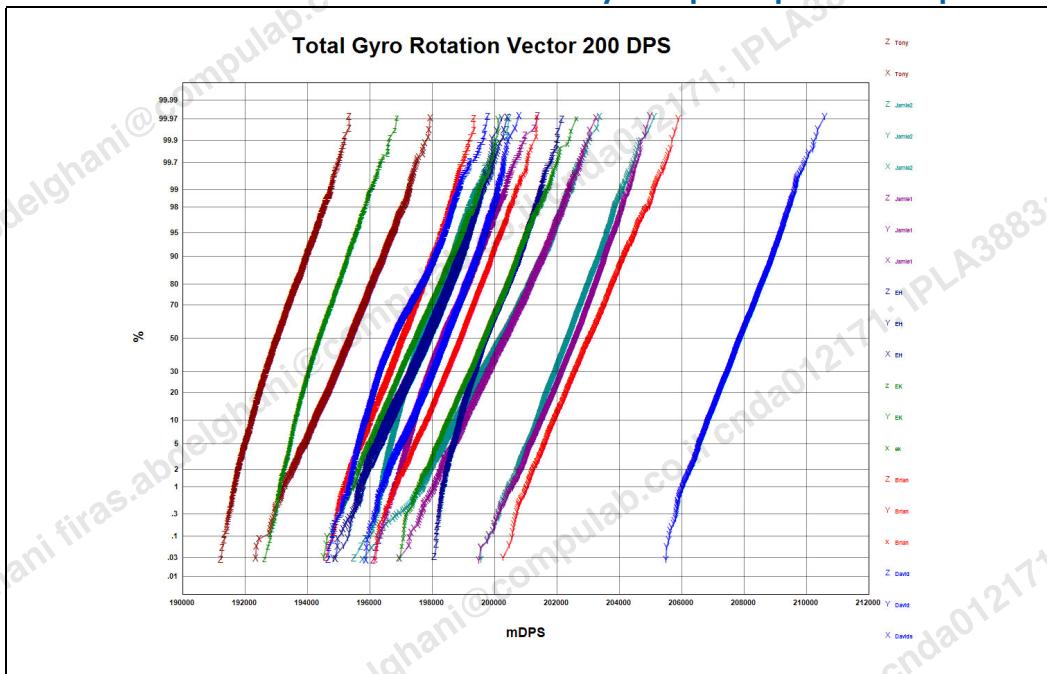
34.7.5.1 Ambient Light Sensors (ALS)

The ability of the ALS to gather light is almost completely determined by the glass/cover, the size and depth of the optical aperture, the use of optical pipes and the quality of the ALS sensor. Inconsistent coating with the glass/cover can cause inconsistent light transmittance. The light transmittance consistency must be with 5% tolerance to avoid per-system calibration.

34.7.5.2 Gyroscope

Measurement of Gyroscope output from several instances of the STM L3GD20H Gyroscope show approximately +-5% variation from the actual rotation rate when measured on [Table 34-3](#). The table shows the cumulative probability distribution of readings from the Gyroscope when rotating at 200 dps.

The measurements show that there is a wide variation in the performance of individual parts. A perfect set of measurements would show a collection of straight vertical lines clustered at 200 dps.

Table 34-3. Rate Table: The cumulative distribution of Gyroscope output at 200 dps

The amount of error was examined at three different speeds which are 60 dps, 200 dps, and 300 dps. The percentage of error remains almost constant with changes in speed. This means that the absolute value of the error observed in gyro measurements will increase with speed. For example, there is almost 8dps variation at 200dps rotation and almost 12dps variation at 300dps rotation.

**Table 34-4. Variations of Gyroscope output at different mDPS**

Ref. value in mDPS	Max/Min/Low M./High M.	Real value in mDPS	Delta	Percent of Error
60,000	Max	64,827	4,827	8%
	Min	55,488	4,512	8%
	Low Median	57,896	2,104	4%
	High Median	62,673	2,673	4%
200,000	Max	210,597	10,597	5%
	Min	191,234	8,766	4%
	Low Median	193,211	6,789	3%
	High Median	207,911	7,911	4%
300,000	Max	314,836	14,836	5%
	Min	286,172	13,828	5%
	Low Median	288,828	11,172	4%
	High Median	311,637	11,637	4%

The variation could be compensated with a simple multiplier. However, finding the amount of variation would require running each instance on a rate table at a known speed and computing scaling terms for each axis. It is difficult and time consuming to perform this procedure on the factory floor.

The sensor fusion core that produces the Orientation, Inclinometer, and Compass virtual sensors uses Gyroscope as the primary input for orientation changes. The fusion algorithms continually crosscheck the Gyroscope against the accelerometer and magnetometer readings to compensate for Gyroscope error. However, if the device enters an area where the magnetometer confidence is low, the error in the Gyroscope may accumulate and result in heading error.

Applications directly using the Gyroscope through the Windows* APIs must anticipate error in the Gyroscope readings.

34.7.5.3 Accelerometer

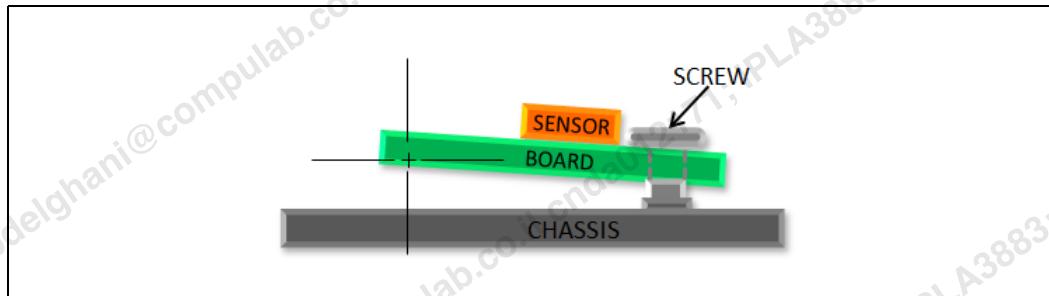
Inconsistent assembly can cause different accelerometer data offset.

Issue Replication Steps:

- System laid flat on leveled surface and Microsoft Sensor Diagnostic Tool showed system appeared to be moving (For example, XYZ accelerometer values are non-zeroes).
- Output from Gyroscope device showed system appeared to be rotating.

Root Cause 1: Sensor device was placed near screw holes.

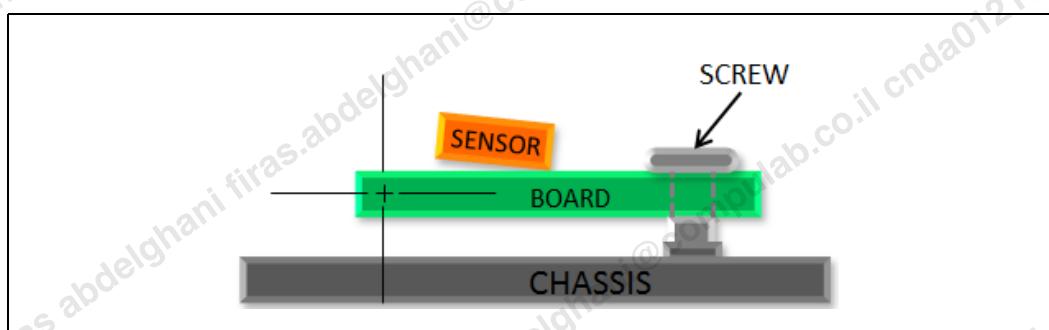
EFFECT: Board bends when screwed to chassis causes the sensor to skew, not leveled in referenced to the chassis.

**WORKAROUND:**

1. Relocate sensor device away from screw hole.
2. Per-System Calibration.

Root Cause 2: Assembly house SMT machines inconsistent placements

EFFECT: Sensors soldered on the board are skewed in referenced to the main board/daughter card.

**WORKAROUND:**

1. Provide tighter SMT machine tolerance level.
2. Per-System Calibration.

34.7.5.4

Pressure Sensors

Pressure sensor is sensitive to air pressure variation, fast heating and light. Please do not place pressure sensor close to fan, speaker and etc that can cause air pressure variation and fast heating part. Please do not expose pressure sensor to light heating.

34.7.5.5

Magnetometer

For the magnetometer enabling challenges refer to Magnetometer Design Integration Challenges - White Paper, RDC#535305.

34.8

System Debug

System debuggability is an important part of the HW design, providing the ability to access the internal parts of the system without harming the system chassis too much. Intel embeds several debug features into its components that requires hardware debug



hooks to be available on the system. This chapter is the design guideline to help the designer to implement Coffee Lake IISS debug hooks on customer's systems. It's for customer's team to be able to debug their systems, if needed.

Also, there are certain issues that customer can not resolve them, and require Intel's assistance to debug it. When system is sent to Intel for debugging, Intel expect these debug hooks to be implemented on customer's system. Otherwise, it will be difficult for Intel to assist within the stipulated time frame.

Debugging Coffee Lake IISS may be divided into two main areas:

- Firmware debug
- Sensor debug

These issues are discussed in the following sections.

34.8.1 Firmware Debug Hooks

The Firmware debug and its debug hooks are fully defined in [Chapter 46, "Platform Debug and Test Hooks"](#).

Note: The Firmware Debug Hook is used to support multiple components on the system, such as the CPU, Intel® ME and etc. It is not specific to Intel® ISH.

34.8.2 Sensors Debug Hooks

Coffee Lake IISS is composed of the embedded Intel® ISH, its communication lines (which are I²C and GPIOs as in below table) to the sensors and the sensors themselves. Accessing sensors traces is required in order to test and/or debug the Coffee Lake IISS system.

Coffee Lake IISS debug is based on connecting debug equipment to the following traces, to resolve issues with sensors.

Connection	Function
ISH_I2C[1:0]	I ² C port [1:0]
ISH_GPIO[15:0]	Up to 4 Interrupt GPIOs due to predefined pins on Intel® ISH Debug Adaptor. The rest of 6 pins are Intel reversed on the same adaptor.
Vio	Sensors Reference Voltage

IISS requires the above traces to be routed to a connector which should be mounted on the system board in an easy accessible location.

For the dense PCB systems, such as is the 2-in-1 (Detachable) and clamshell systems, a solution involving an adaptor that is proposed, as defined in [Section 34.8.2.1](#).

For a less dense PCB systems, as are the pAIO and AIO systems, the customer may select if to adopt the adaptor solution as in [Section 34.8.2.1](#) or a solution of placing a simple 0.1" header on the pAIO or AIO PCB, as described in [Section 34.8.2.2](#).

Not implementing one of the debug connectors as proposed above will limit the customer in debugging system and will limit Intel debug team in supporting the customer when brought it to Intel for assistance. When system is sent to IISS debug team, a debug connector is expected to be available and accessible.

The debug connector may be eliminated from production systems. Therefore, customer is proposed to replace it with test pads. For easy blue wire soldering, in case more validation or debug will be required. It is proposed to clearly mark these test pads with silk screen writing on the PCB for easy identification.

34.8.2.1 Sensors Debug Hooks for 2-in-1 (Detachable) and Clamshell Systems

All the 2-in-1 (Detachable) and clamshell systems (and some pAIO systems too) are dense systems, enclosed inside a chassis which is very delicate and may be damaged when opening chassis for accessing internal traces on debugging.

To overcome this problem, Intel recommend customer placing a small connector on the PCB, to provide all the sensor debug traces located in an easily accessible location, such as under the keyboard (Figure 34-16), inside the DDR compartment, the WLAN module compartment or the SSD compartment.

In order to access this connector to share the traces on the connector with external test/debug equipment, Intel developed an adapter (Figure 34-15), providing the ability for the external test/debug equipment to connect the connector on the main board. To obtain such adaptor, please contact local Intel® ISH AE.

Figure 34-15.Adapter and Ribbon Cable



When the system gets to the production stage, and if the Coffee Lake IISS is fully functional and was fully validated on pre-production systems, the debug connector may become "UN_STUFF" (meaning, not being placed on the board). It is, however, recommended to leave connectors' footprint on the system board layout without being populated, in case future debug is required.

Note: Solder the debug connector to the footprint, if the system is going to be sent to Intel, for IISS debug support.

The connector to use on the main board is a 18-pin FPC/FFC Lower Side Contact, Side Entry, Surface Mount ZIF Connector with a 0.5 mm pitch, such as the 10051922-1810elf, and using the pinout shown in Table 34-5. This connector should be placed in an easy accessible location as described above.

Optional Locations of the ZIF Connector

The ZIF connector may be placed on the system in location where it will be easy to connect the adapter and hopefully will not require opening the chassis to access it. The adapter will then be extend out of the chassis, so the connection of test/debug equipment will be direct to the 0.1" spacing header which is part of the adapter. Figure 34-16 through Figure 34-19 propose optional locations and connecting technologies.

Figure 34-16. Proposed Location for ZIF Connector - under the keyboard

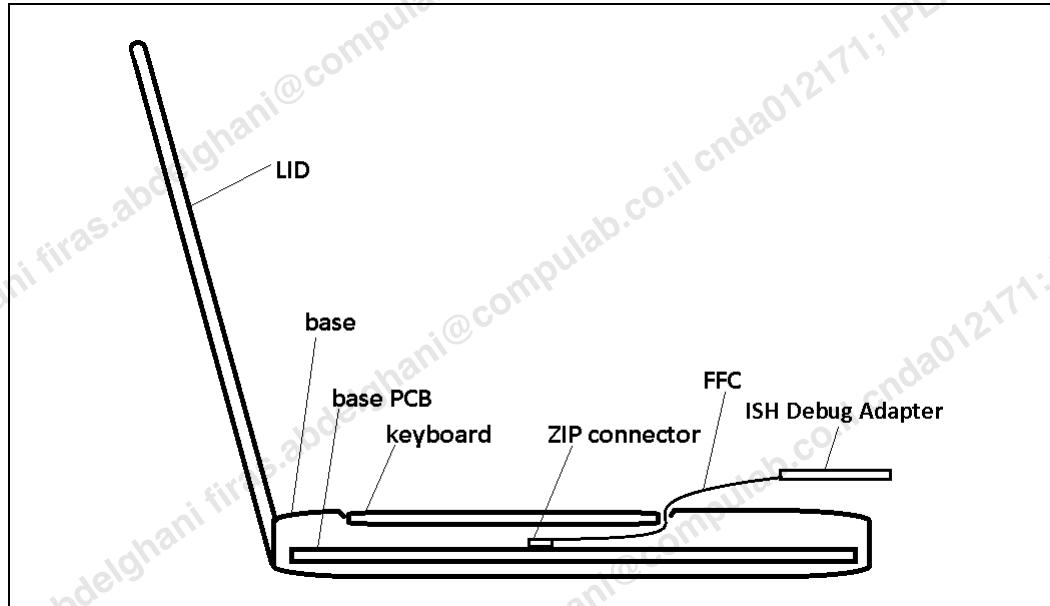


Figure 34-17. Proposed Location for ZIF Connector - under the keyboard

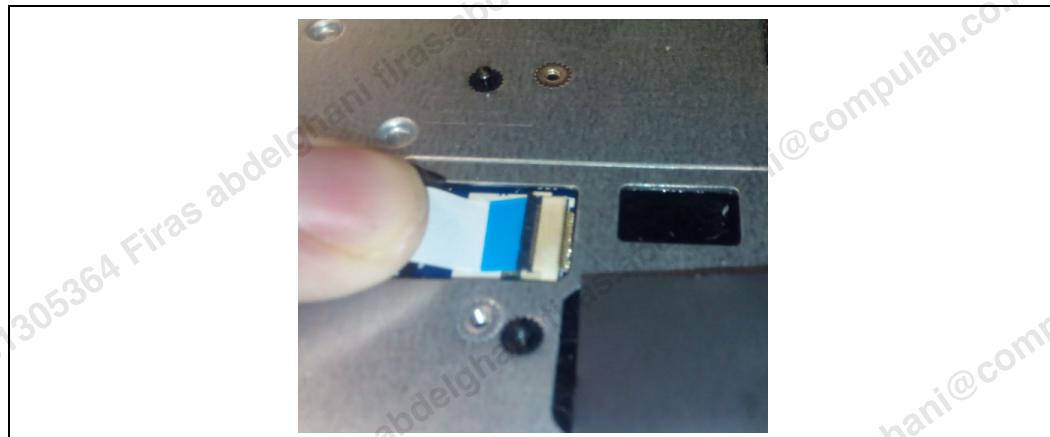


Figure 34-18.Connecting Debug Adaptor to an I²C sniffer



Figure 34-19.Proposed Usage of ZIF Connector Inside SST Compartment



Once the 0.1" header part of the adapter is out of the chassis, it is now easy to hook debug equipment (Such as an I²C sniffer or an oscilloscope channel) to it, as in Figure 34-20, for a debug session.

Figure 34-20.Connecting Test/Debug Equipment to the Adapter

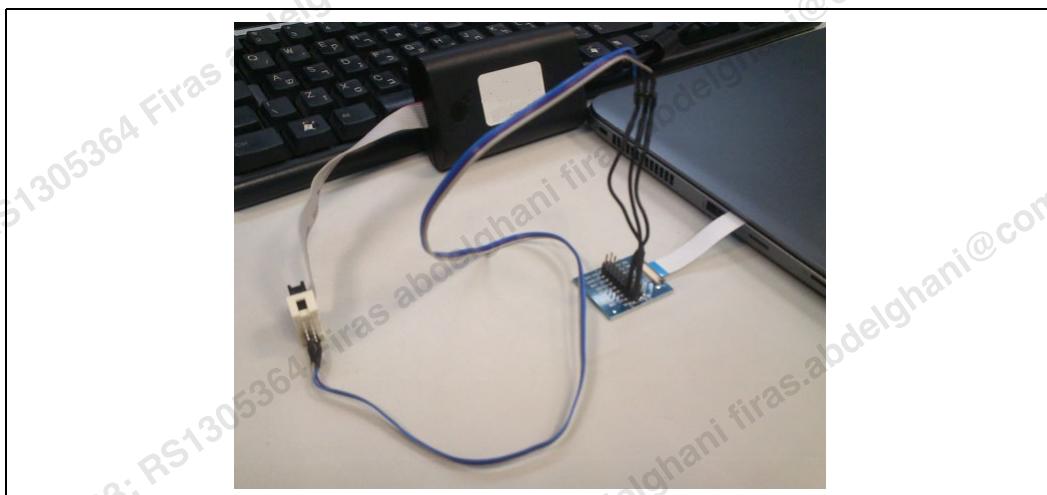




Table 34-5 defines the pin configuration of the external 2x9 pin 0.1" spacing header.

Table 34-5. Pin Location for Dual-in-Line Connector

Signal Name	Pin	Header	Pin	Signal Name
ISH_I2C0_SCL	1		2	ISH_I2C0_SDA
ISH_I2C1_SCL	3		4	ISH_I2C1_SDA
GND	5		6	GPIOa
GPIOb	7		8	GPIOc
GPIOd	9		10	GND
Reserved by Intel	11		12	Reserved by Intel
Reserved by Intel	13		14	Reserved by Intel
Reserved by Intel	15		16	Reserved by Intel
GND	17		18	Vio

Table 34-6 defines the pin configuration of the internal 18 pins ZIP connector.

**Table 34-6. 18-pin ZIF Connector Pinout**

Pin	Pin function	Description
1	ISH_I2C0_SCL	Clock line for the I2C0
2	ISH_I2C0_SDA	Data line for the I2C0
3	ISH_I2C1_SCL	Clock line for the I2C1
4	ISH_I2C1_SDA	Data line for the I2C1
5	GND	System Ground
6	GPIOa ⁽¹⁾	Connect here one of the GPIOs in use
7	GPIOb ⁽¹⁾	Connect here one of the GPIOs in use
8	GPIOc ⁽¹⁾	Connect here one of the GPIOs in use
9	GPIOd ⁽¹⁾	Connect here one of the GPIOs in use
10	GND	System Ground
11	Reserved by Intel	Do not use
12	Reserved by Intel	Do not use
13	Reserved by Intel	Do not use
14	Reserved by Intel	Do not use
15	Reserved by Intel	Do not use
16	Reserved by Intel	Do not use
17	GND	System Ground
18	Vio	Sensors Reference Voltage

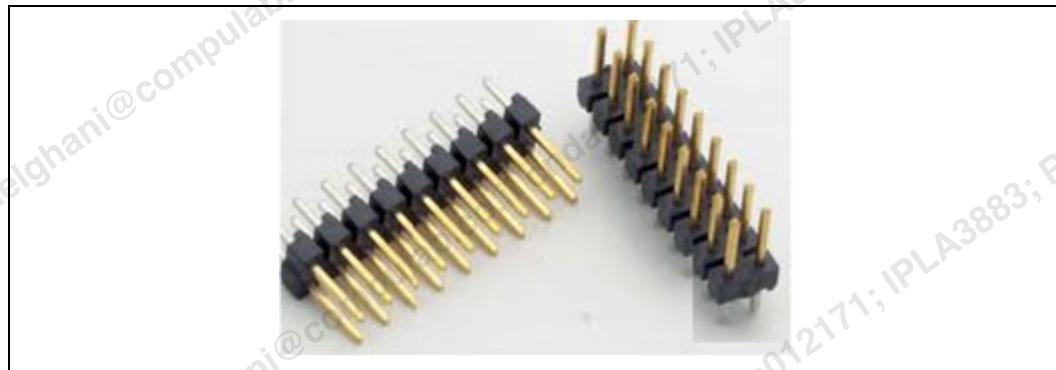
Notes:

1. GPIOa, GPIOb, GPIOc and GPIOd are place holders for customer design GPIOs. Customer should connect to these pins his Intel® ISH GPIOs, to be able to connect them to a debug equipment, at the time of need.
2. It is strongly recommended that the name 'Coffee Lake Intel® Integrated Sensor Solution' be labeled in silk screen next to the ZIF connector and/or pads, and each pin name clearly marked in silk screen on the board.

34.8.2.2**Sensors Debug Hooks for pAIO and AIO Systems**

pAIO and AIO form factors are less dense so the adaptor solution that was proposed for the 2-in-1 (Detachable) and clamshell systems may be too complicated and not needed.

It is recommended to use a single 18-pin (2 rows of 9 pins) male 0.1" header with pin width of 64 mm, pin height of 5.84 mm and a 2.54 mm distance (pitch) between pins, as shown in [Figure 34-21](#), using the pinout shown in [Table 34-7](#). These pins connect directly to the Sensor debug equipment, such as sniffer or a scope. The Intel® ISH Debug Adapter is not necessary.

**Figure 34-21.Dual-in-Line Header Example****Table 34-7. Pin Location for Dual-in-Line 0.1" Header**

Signal Name	Pin	Header	Pin	Signal Name
ISH_I2C0_SCL	1		2	ISH_I2C0_SDA
ISH_I2C1_SCL	3		4	ISH_I2C1_SDA
GND	5		6	GPIOa
GPIOb	7		8	GPIOc
GPIOd	9		10	GND
Reserved by Intel	11		12	Reserved by Intel
Reserved by Intel	13		14	Reserved by Intel
Reserved by Intel	15		16	Reserved by Intel
GND	17		18	Vio

34.9 Intel® ISS Checklists

This section provide schematics, PCB Layout and System checklists for the Coffee Lake IISS design to support in the design review and provide additional filter to catch design errors. Intel recommends that customer will make the best design according to the design guidelines provided, will run over the following checklist and will consult with Intel Field Application Engineers if there is any violation to the IISS Design Guidelines.

When to use this Checklist?

- Schematics: to be performed after schematics is done before PCB Layout design.
- PCB Layout: to be performed after chassis and PCB layout are done before Gerber.
- System: to be performed after system is fully assembled and powered.

Notes:

1. Please be noticed on your early designs. It is strongly recommended to reserve pads of series resistor and stuff with 0 Ohm resistors on Intel® ISH I²C clock and Intel® ISH I²C data lines. Designers could separate sensor components onto ISH_I2C0 and ISH_I2C1. By doing this, it can keep flexibility of circuits if an adjustment is needed on your PCB.
2. For the Magnetometer, a special white paper was composed, to support Magnetometer integration. Refer to RDC#535305.



34.9.1 Schematics Design Checklists

All labels may be prefixed with ISH_ if needed to differentiate them from other system schematic labels.

34.9.1.1 General Schematics Checklists

This section is used to record the actual sensors that the designer selected to use on his/her design. Based on the sensor used, the following tables should be filled by the designer with the specific selected sensors data.

Table 34-8. Ambient Light Sensor (ALS) Details

Ambient Light Sensor (ALS)	Data	Comments
Sensor Part number?		
I ² C bus the Sensor is connected to?		
I ² C address on the i2C bus?		
Is there an option to use alternative I ² C Address? If so, what is the alternative I ² C Address?		
Interrupt function? (such as Wake or free-fall or Motion detection, etc.)		
Interrupt polarity? (Active high or active low)		
Interrupt I/O buffer type? (Totem Pole or Open drain)		
Is the same interrupt line shared with other component(s)? Intel strongly do not recommend it and support it.		
VDD voltage? (Typically 3.3V)		
VDDIO voltage? Either 1.8V or 3.3V should be same for all sensors connected to the same I ² C.		

Table 34-9. Gyroscope Details

Gyroscope	Data	Comments
Sensor Part number?		
I ² C bus the Sensor is connected to?		
I ² C address on the i2C bus?		
Is there an option to use alternative I ² C Address? If so, what is the alternative I ² C Address?		
VDD voltage? (Typically 3.3V)		
VDDIO voltage? Either 1.8V or 3.3V should be same for all sensors connected to the same I ² C.		

Table 34-10. Magnetometer Details (Sheet 1 of 2)

Magnetometer	Data	Comments
Sensor Part number?		
I ² C bus the Sensor is connected to?		
I ² C address on the i2C bus?		
Is there an option to use alternative I ² C Address? If so, what is the alternative I ² C Address?		
VDD voltage? (Typically 3.3V)		

**Table 34-10. Magnetometer Details (Sheet 2 of 2)**

Magnetometer	Data	Comments
VDDIO voltage? Either 1.8V or 3.3V should be same for all sensors connected to the same I ² C.		

Table 34-11. Accelerometer Details

Accelerometer	Data	Comments
Sensor Part number?		
I ² C bus the Sensor is connected to?		
I ² C address on the i2C bus?		
Is there an option to use alternative I ² C Address? If so, what is the alternative I ² C Address?		
Interrupt function? (such as Wake or free-fall or Motion detection, etc.)		
Interrupt polarity? (Active high or active low)		
Interrupt I/O buffer type? (Totem Pole or Open drain)		
Is the same interrupt line shared with other component(s)? Intel strongly do not recommend it and support it.		
VDD voltage? (Typically 3.3V)		
VDDIO voltage? Either 1.8V or 3.3V should be same for all sensors connected to the same I ² C?		

Table 34-12. Pressure Sensor Details

Pressure Sensor	Data	Comments
Sensor Part number?		
I ² C bus the Sensor is connected to?		
I ² C address on the I ² C bus?		
Is there an option to use alternative v Address? If so, what is the alternative I ² C Address?		
VDD voltage? (Typically 3.3V)		
VDDIO voltage? Either 1.8V or 3.3V should be same for all sensors connected to the same I ² C?		

Table 34-13. Optional 2nd Accelerometer (for 360° hinge designs) (Sheet 1 of 2)

2 nd Accelerometer	Data	Comments
Sensor Part number?		
I ² C bus the Sensor is connected to?		
I ² C address on the i2C bus?		
Is there an option to use alternative I ² C Address? If so, what is the alternative I ² C Address?		
Interrupt function? (such as Wake or free-fall or Motion detection, etc.)		
Interrupt polarity? (Active high or active low)		
Interrupt I/O buffer type? (Totem Pole or Open drain)		

**Table 34-13. Optional 2nd Accelerometer (for 360° hinge designs) (Sheet 2 of 2)**

2 nd Accelerometer	Data	Comments
Is the same interrupt line shared with other component(s)? Intel strongly do not recommend it and support it.		
VDD voltage? (Typically 3.3V)		
VDDIO voltage? Either 1.8V or 3.3V should be same for all sensors connected to the same I ² C		

Table 34-14. Intel Sensor Solution BOM Checklist

Schematic Notes	✓	Customer Feedback	Intel Feedback
Are all the Intel® ISH managed sensors supported in Intel POR BOM on specific platform (ex: KBL, CNL, etc.)?			
Did you make sure you or your vendor will provide support to you with Intel® ISH FDK if your selected sensor/sensors is/are not in Intel POR BOM?			
Did you make sure there are no 2 sensors using the same I ² C address on the same Intel® ISH I ² C bus?			
Did you review the I ² C design and make sure it conforms to the I ² C Design Guidelines as in the "I ² C Interface Design Guidelines" in Coffee Lake PDG?			

Table 34-15. Sensors Debug Connector Checklist

Schematic Notes	✓	Customer Feedback	Intel Feedback
Was one of the 2 Sensors debug connectors options implemented in this design? Refer to "Sensors Debug Hooks" in Coffee Lake PDG.			

Table 34-16. FW Debug connector Checklist

Schematic Notes	✓	Customer Feedback	Intel Feedback
Was the XDP or the Primary CMC Debug Solution implemented? Refer to "Platform Debug and Test Hooks" for details in Coffee Lake PDG.			

34.9.1.2 Detailed Schematics Checklists

Table 34-17. General Checklist

Schematic Notes	✓	Customer Feedback	Intel Feedback
Did you read, understood and followed all your sensors manufacturers design guidelines?			
Did you add Layout instructions to the schematics, for the layout designer to implement, such as keep-out zones for sensors, as mentioned in "System Debug" in Coffee Lake PDG?			
Did you check that all the sensors that are located on the same I ² C bus, can they operate in the selected frequency?			

**Table 34-17. General Checklist**

Schematic Notes	✓	Customer Feedback	Intel Feedback
Did you correctly set the Address Selection pin on each of the sensors, to the correct level, to be accessible on its selected address?			

Table 34-18. Power Rails Checklist

Schematic Notes	✓	Customer Feedback	Intel Feedback
Intel® ISH I ² C interfaces support either 1.8V or 3.3V voltage, but not mixing. Did you check that all sensors support the same voltage, or you have provided voltage level shifter?			
Did you understand and follow all the layout and design rules requirements from the sensor manufacturers?			

Table 34-19. Coffee Lake Sensors Interrupt/GPIO Checklist

Schematic Notes	✓	Customer Feedback	Intel Feedback
Are all sensors' INT pins configured correctly, as mentioned in "Electrical Characteristics" in Coffee Lake Platform PDG?			
Optional, are all Sensors INT pins on the same GPIO using the same I/O type (Totem Pole, Open Drain), polarity (Active High or Active Low) and voltage (1.8V or 3.3V)?			

34.9.2 PCB Layout and System Design Checklists

The PCB Layout and System design checklist is documented to provide our customer's PCB Layout and System design assistance to verify that the customer will produce the best accuracy reading sensor data, by followed the IISS system design guidelines. We recommend that customer will make the best design according to the design guidelines provided and will consult with Intel Application Engineer, if this PCB Layout and System check results violates IISS design guidelines. Not following design guidelines will result in a system with **less** than best performance possible.

When using sensors package that contains 2 or more sensors, this package should conform to the design guidelines for both sensors, so both sensors checklists should be used for that package.

34.9.2.1 When to Use this Checklist?

Use this checklist as follows:

- After board's components are placed (according to the design guidelines), before PCB Layout starts.
- After PCB Layout was done, before closing the PCB design for gerber files.
- During and after system's chassis design, for LID magnets, hinges, speakers, microphone, fan, cooling system, hot spots location, wireless charger and digitizers, that may impact sensors accuracy.
- On any PCB Layout change.
- On any Chassis re-design.

**Note:**

For the Magnetometer, a special white paper was composed, to support Magnetometer integration. It provides a concept on how and when to use the MLOT tool/Concept. Refer to RDC#535305.

34.9.2.2 Sources to this PCB Layout and System Checklist:

This System and PCB Layout checklist is based on the following sources:

- Schematics checklist.
- Sensor vendors documentation.
- Accumulated knowledge and experience gathered by Intel Application Engineers.

Intel Application Engineers will be more than happy to hear customer's inputs on any aspect of sensors, to better serve customers in the next platform.

34.9.2.3 PCB Layout and System Checklists:**General Mechanical Sensor Placement and Assembly Checklist**

Checklist	✓	Customer Feedback	Intel Feedback
PCB Layout			
Did you read, understand and follow all the layout and design rules requirements from your sensor manufacturers?			
Did you read and understand the "Magnetometer Design Integration - Technical White Paper", RDC#535305?			
Did you make sure that the sensor placement was the first step when outlining a new PCB layout and system Chassis? You need to plan accordingly, accommodating both board and system level.			
In the Chassis level, did you place sensors at an interference-free location, in the system in all its usage models ?			
Did you avoid placing the sensors in a long and narrow region of PCB? From our learning shows that doing this can warp and cause sensor package stress which may cause drift.			
Did you avoid placing the sensor near a connector and screw hole? Doing it will cause unsymmetrical stress coming from PCB deformation when screw is inserted will cause drift.			
Did you avoid placing the sensor in a region of PCB that can warp? Doing it might cause sensor package stress which may cause shift.			
System Layout			
Were all sensors placed 2 or 3 cm away from any hot devices? This helps to avoid large temperature gradient.			
Did you make sure that sensors are not placed in a region of PCB that can warp? It can cause package stress which may cause shift.			



Checklist	✓	Customer Feedback	Intel Feedback
Did you make sure that sensors are not placed near a connector or screw hole? It can cause an unsymmetrical stress coming from PCB deformation and may cause drift.			
For a 360° system, checklist defined in the PCB Layout above should be run for all usage models, meaning Lid is in 0°, 180° and 360° etc.			
For a Detachable (2-in-1) system, checklist defined in the PCB Layout above should be run for all usage models, meaning Tablet mode, Laptop mode where Lid is at 0° (Lid closed), 90° and the maximum.			

34.9.2.3.1 Ambient Light Sensor - ALS

Checklist	✓	Customer Feedback	Intel Feedback
System Layout			
Is the ALS placed in the lid or display module, close to the camera (if present) and facing the user? This will allow effective control of screen brightness based on ambient light.			
Are the view angle and the lens meeting the spec of the ALS?			
Is the glass or plastic covering material consistent across the units of the same SKU/Model?			
Is the aperture wide enough to detect light without significant attenuation when the light source is at an angle to the device or from a diffused source?			
Are the glass/cover and the sensor aligned? (a misalignment would mask out some of the light and produce unexpected readings from the ALS)			
If optical film or ink coating are applied to hide the ALS optical cavity, is the filter designed to allow at least 80% of visible wavelength light to pass?			

34.9.2.3.2 Gyroscope

Checklist	✓	Customer Feedback	Intel Feedback
PCB Layout			
Is the Gyroscope mounted securely, so it can not move independently?			
System Layout			
Are the Gyroscope X, Y and Z axes orientated as described in the PDG?			
Is the Gyroscope placed in a stable position, isolated from any vibration, including transmitted vibration, air pressure change vibration, etc.?			
Is the Gyroscope place at least 30 mm away from audio speakers, fans, and haptic vibration motors?			



Accelerometer

Checklist	✓	Customer Feedback	Intel Feedback
PCB Layout			
Is the Accelerometer mounted securely, so it can not move independently?			
System Layout			
Are the Accelerometer X, Y and Z axes orientated as described in the PDG?			
Is the Accelerometer placed in a stable position, isolated from any vibration, including transmitted vibration, air pressure change vibration, etc.?			
Is the Accelerometer place at least 30 mm away from audio speakers, fans, and haptic vibration motors?			

34.9.2.3.3 Magnetometer

Checklist	✓	Customer Feedback	Intel Feedback
PCB Layout			
Have you read and understood the Magnetometer Design Integration - Technical White Paper, RDC#535305?			
The Magnetometer can easily become an issue if the design guidelines are not followed. Did you follow all of the Design Guidelines provided in the PDG?			
Was the magnetometer placement the first step when outlining a new PCB layout?			
Was the magnetometer placed at least 40 mm away from any rare earth magnets (Hard Iron such as speaker magnets, LiD magnets, fan, Hall Effect magnet etc.)?			
Was the Magnetometer placed at least 30 mm away from any large/thick (structural) ferrous metals, the components which includes the magnet of a hard disk, digitizer, and any components with the magnetism of 100 Gauss?			
Was the Magnetometer placed at least 10 mm away from the components which include microphone, vibration motor, magnetic switch, transformer, camera module, beeper, battery, SAW filter, antenna, power amplifier, choke, LCD rear case and any components with the magnetism of 5 Gauss?			
Was the Magnetometer placed at least 5 mm away from the components which include Memory/SIM card socket, USB connector, other connectors, screw, nut, spring, EMI shielding part, and any components with the magnet-conductive material (Iron, Cobalt, Nickel)?			
Was the Magnetometer placed at least 2 mm away from the surrounding resistor and capacitor? This, since nickel plating is usually present on solder end caps of surface mount components?			



Checklist	✓	Customer Feedback	Intel Feedback
Was the Magnetometer placed at least 10 mm away from the power trace (including power plane) on all the PCB layers, components on both PCB sides or out of the board with the variable current higher than 10 mA?			
Was the Magnetometer placed at least 20 mm away from the power trace (including power plane) on all the PCB layers, components on both PCB sides or out of the board with the variable current higher than 100 mA?			
Was the Magnetometer placed at least 25 mm away from the power trace (including power plane) on all the PCB layers, components on both PCB sides or out of the board with the variable current higher than 200 mA?			
Is there any power or ground plane under or nearby the Magnetometer? (There should be none)			
Make sure the Magnetometer is not covered with any material that can block the static magnetic field from the earth.			
System Layout			
Did you make sure that the LCD screen back shell, shield (for RF, BT...), mechanical part (key, screw, connector) do not contain ferromagnetism material (Fe, Co, Ni)? (correct answer is no)			
Did you perform the same test as in the PCB layout when the PCB is inside the final chassis, when system is powered?			
All the above tests must be checked in all usage models, such as a 360° system, interference for the Lid located Magnetometer should be checked with Lid in 0°, 180° and 360°.			

34.9.2.3.4 Pressure Sensor

Checklist	✓	Customer Feedback	Intel Feedback
System Layout			
Is the clearance above the metal lid less than 0.1mm?			
Is the sensor located in a section where appropriate venting exists?			
Is the sensor located in an area where liquids may come into direct contact with the device?			
Is there a direct light heating the sensor? Direct light can influence the accuracy of the measurement (photo-current of silicon).			
Is the sensor located near a source of fast air pressure variation, such as fans, speaker etc.?			
Is the sensor located near a source of fast heating parts with gradients higher than 3°C/sec?			
Is the PCB area below the sensor defined as keep-out area?			

**34.9.2.3.5 Debug Connector (10051922-1810elf)**

Checklist	✓	Customer Feedback	Intel Feedback
PCB Layout			
Was the connector implemented on the PCB?			
System Layout			
Was the connector placed in an area where accessing it does not require opening the chassis?			

§ §



35 Discrete Trusted Platform Module (TPM) Design Guidelines

Trusted Platform Module (TPM) is a Trusted Computing Group (TCG) low cost security solution to increase confidence on system security. The Trusted Platform Module (TPM) is a device that resides on the motherboard and is connected to PCH using the Low Pin Count (LPC) bus to communicate with the rest of the platform.

Today most protection against computer viruses and unauthorized intrusions consists of adding and updating software that installs outer barriers and surveillance tools. The goal of Safer Computing is to go much deeper, integrating a level of trust into the actual hardware and pre-operating system environments. Applications intended for e-business are based on trust in the communication partner and the reliability of the connection.

The objective of the TPM is to establish a baseline of platform integrity and enhance system security. TPMs are available from several integrated circuit vendors in the form of a silicon component and accompanying software. When integrated into the PC, a Trusted Platform Module provides protected storage of platform data allowing for platform-level authentication toward the goal of making data files, transactions and communication more trustworthy.

For more information on trusted platform modules and Safer Computing, refer to the trusted computing group web site: <http://www.trustedcomputinggroup.org>.

Table 35-1. TPM Reference Documents

Title	Location
TCG Architecture Overview, Version 1.4	http://www.trustedcomputinggroup.org
TCG Design, Implementation, and Usage Principles (Best Practices)	http://www.trustedcomputinggroup.org

Table 35-2. TPM Compliance Documents

Title	Location
TPM Main Specification	http://www.trustedcomputinggroup.org

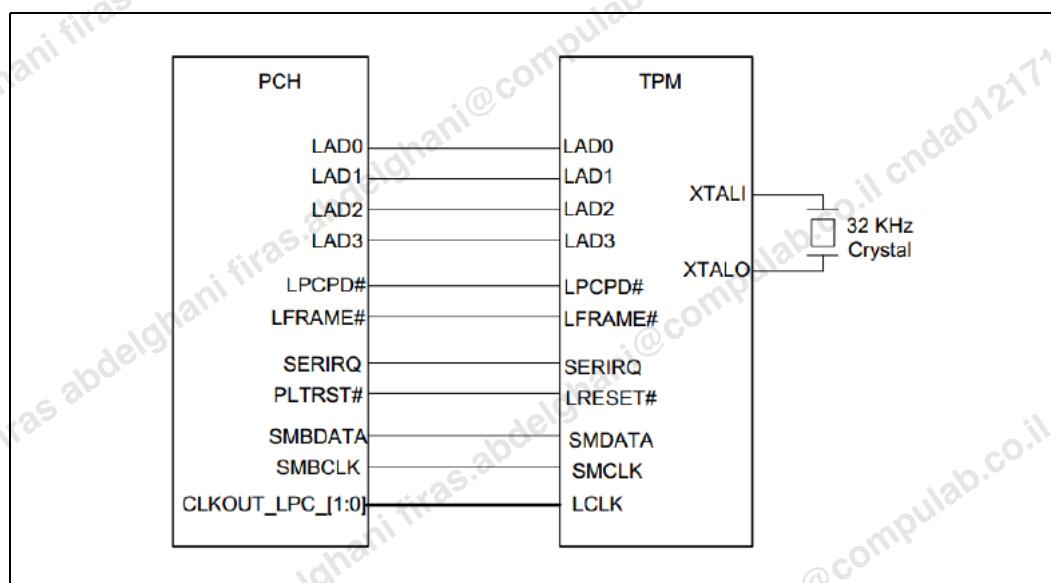
35.1 Signal Description

35.1.1 Signal Groups

Table 35-3. Trusted Platform Module (TPM) Signals

Section	Group	Signal Name	Description
Refer figure below	Address data	LAD[3:0]	Address/Data lines
	Clock	LCLK	Clock
	Reset	LRESET	Reset
	Control	LFRAME#	Cycle termination
		SERIRQ	Serialized IRQ
		LPCPD#	Suspend status and LPC power down

Figure 35-1. Trusted Platform Module (TPM) / PCH Block Diagram



§ §



36 Platform Reset Considerations

Platform reset signals is a group of reset signal that control power on sequence, power management and provide proper reset to all components on the platform. This chapter provide detailed guideline on how to generate and use platform reset signal to ensure functionality of the platform.

36.1 Signal Description

36.1.1 Signal Groups

Signals listed in the following table are identified as platform reset signals from the PCH.

Table 36-1. Platform Reset Signals

Group	Signal Name	Description
Reset	RSMRST#	Resume Well Reset: This signal resets the Primary Well
	SYS_RESET#	System Reset
	PLTRST#	Platform Reset
	DRAM_RESET#	DRAM Reset
Power Management	ACPRESENT	ACPRESENT
	BATLOW#	Battery Low
	PCH_PWROK	PCH Power OK
	DSW_PWROK	Deep Sleep Well Power OK
	SYS_PWROK	System Power OK
	SLP_A#	ASW Sleep Control
	SLP_S0#	S0 Sleep Control
	SLP_S3#	S3 Sleep Control
	SLP_S4#	S4 Sleep Control
	SLP_S5#	S5 Sleep Control
	SLP_LAN#	LAN Sub-System Sleep Control
	SLP_WLAN#	WLAN Sub-System Sleep Control
	SLP_SUS#	Deep S3/S4/S5 Indication. Primary Well power control on Deep Sx enabled platform.
	PWRBTN#	Power Button
	SUSACK#	Deep S3/S4/S5 entry Acknowledge
	SUSPWRDNACK/SUSWARN#	Deep S3/S4/S5 Power Down Warning to EC.
	SUSCLK	This clock is an output of the RTC generator circuit for use by other platform devices for clock refresh.



36.2 Additional Guidelines

36.2.1 SYS_RESET# Usage Model

Designers can connect the System Reset signal (SYS_RESET#) on PCH directly to the reset button on the system, provided that there is a weak 8.2 K Ω -10 K Ω pull-up resistor to Primary 3.3 V (VCCPRIM_3p3) or pull-up to any 3.3V rails that is controlled by SLP_S3# or SLP_S4# or SLP_S5# signals. PCH will de-bounce signals on this pin (16 ms) and allow the SMBus to go idle before resetting the system; thus helping prevent a slave device on the SMBus from “hanging” due to the PCH being reset in the middle of a cycle.

When SYS_RESET# is connected to a XDP header, it will require a stronger pull up to work with ITP hardware. Use 100 Ω - 3 K Ω pull-up whenever it is connected to a XDP header. Recommend to use 3 K Ω to minimize leakage.

36.2.2 SLP_A# Usage Model

SLP_A# is a PCH signal that may be used to control the overall power to Intel® Management Engine (Intel® ME) components during ACPI S3 through S5 states when Intel ME is enabled. When asserted, it indicates platform level devices on the Active Sleep Well (ASW) maybe powered off.

Note: The PCH no longer have a dedicated ASW rail. Refer to [Chapter 33, “Intel® Management Engine \(Intel® ME\)”](#) for details regarding SLP_A# connection.

36.2.3 SLP_S0# Usage Model

SLP_S0# is a PCH signal which indicates the system is in the S0ix state. It is used primarily to control platform VR so that it will enter a more power efficient mode during S0ix. It may also be used to power off all non-critical components during the S0ix state. This signal should be connected to an VR controller to enter low power mode.

36.2.4 SLP_S3# Usage Model

SLP_S3# is a PCH signal which indicates the system is in the ACPI S3 State. It is used to power off all non-critical components during the S3 state. This pin may be connected to an SIO to indicate the S3 state. Refer to PCH EDS for additional information.

36.2.5 SLP_S4# Usage Model

SLP_S4# is a PCH signal which indicates the system is in the ACPI S4 State. It is used to power off the DRAM and other non-critical components during the S4 state. This pin can be connected to an SIO to indicate the S4 state. Refer to PCH EDS for additional information.

36.2.6 SLP_S5# Usage Model

SLP_S5# is a PCH signal which indicates the system is in the ACPI S5 State. It maybe used to power off non-critical components during the S5 state. This pin can be connected to an SIO to indicate the S5 state. If S5 state indication is not required this pin may be left as no connect or configured as GPIO. Refer to PCH EDS for additional information.



36.2.7 SLP_LAN# Usage Model

SLP_LAN# is a PCH signal which indicates when the Intel LAN PHY device must be powered. This pin should be connected to a power switch to control the 3.3V and any other externally supplied voltages to the external Intel LAN PHY. SLP_LAN# is always de-asserted when SLP_S3# and/or SLP_A# is de-asserted. SLP_LAN# can also be configured by Intel ME FW or host BIOS to indicate when the Intel LAN PHY should be powered in S3-S5 to support WOL (Host or Intel ME).

36.2.8 SLP_WLAN# Usage Model

SLP_WLAN# is a PCH signal which indicates when the Wireless LAN device must be powered. This pin should be connected to a power switch to control the 3.3V and any other externally supplied voltages to the external Wireless LAN. SLP_WLAN# is always de-asserted when SLP_S3# and/or SLP_A# is de-asserted. SLP_LAN# can also be configured by Intel ME FW or host BIOS to indicate when the Wireless LAN should be powered in S3-S5 to support Wake on Wireless LAN (Host or Intel ME).

36.2.9 SLP_SUS# Usage Model

SLP_SUS# is a PCH signal which indicates that the system is in Deep Sx state. The Deep Sx state is a lower power, limited wake capability supported state where the Primary well is powered off and only the DSW well in the PCH remains powered. This pin can be used to power off Primary power during the Deep Sx state. If Deep Sx is not implemented on the platform, this signal may be left as no connect. Refer to PCH EDS for additional information.

36.2.10 SUSWARN# / SUSPWRDNACK Usage Model

SUSWARN# is a PCH signal which indicates the PCH is planning to enter into Deep Sx state and power off the Primary well. The Embedded Controller (EC) monitors this signal and appropriately controls power to the Primary rails. This signal is only used on platforms that support the Deep Sx state.

This signal is multiplexed with SUSPWRDNACK, since SUSPWRDNACK is not needed in Deep Sx supported platforms.

36.2.11 SUSACK# Usage Model

SUSACK# is an input signal to the PCH from the Embedded Controller (EC), acknowledging that the EC has completed preparations as signaled by SUSWARN#. This signal is only used on platforms that support the Deep Sx rate.

Note: SUSACK# and SUSWARN# can be tied together if EC does not want to be involved in the handshake mechanism for the Deep Sx state entry and exit.

36.2.12 PWRBTN# Usage Model

The Power Button signal (PWRBTN#) on PCH can be connected directly to the power button on the system. When system power button is pressed, PWRBTN# should be pulled low. This signal is internally pulled-up in PCH to VCCDSW_3p3 through a weak pull-up resistor (15 kΩ to 40 kΩ). PCH has 16 ms of internal de-bounce logic on this pin, external debouncing circuit is not required.



36.2.13 PLTRST# Usage Model

The Platform Reset signal (PLTRST#) is a signal on the PCH that should be connected to devices on the motherboard which require a reset. For designs with large fan out on PLTRST#, proper validation should be carried out to ensure the output driving capability of PLTRST# is not exceeded. A buffer will be needed if PLTRST# driving capability is exceeded.

Note: Some devices may utilize GPIOs to control the resets during RTD3.

36.2.14 SUSCLK Usage Model

On CFL, the SUSCLK signal has moved to the DSW well and is generated from the RTC. For platforms supporting Deep Sx and utilizing this signal, proper isolation must be taken to ensure SUSCLK is not driven into a device that might be powered off in Deep Sx state.

36.2.15 RSMRST# Generation

RSMRST# is an input signal to the PCH generated by EC. This signal is used for resetting the Primary power plane logic. It must be asserted for at least 10ms after Primary power wells are stable.

36.2.16 DSW_PWROK Generation

DSW_PWROK is an input signal to the PCH generated by EC to indicate that DSW rail, is stable on the platform. For platforms not supporting Deep Sx, connect directly to RSMRST#. The DSW rails must be stable for at least 10 ms before DSW_PWROK is asserted to PCH.

36.2.17 PCH_PWROK Generation

PCH_PWROK is an input signal to the PCH generated by EC based on VR power good signal. Assertion of this signal indicates that all the PCH Primary rails are up and all the main CPU rails (excluding GT and core) are up.

36.2.18 SYS_PWROK Generation

This is an input signal to the PCH and provides a platform/EC a mechanism to stall the PCH de-assertion of PLTRST# to the platform. While PCH_PWROK always indicates that the Primary well of the PCH and CPU rails (excluding core and GT) are stable, SYS_PWROK is used to inform the PCH that power is stable to some other system component(s) and the system is ready to start the exit from reset. The particular component(s) associated with SYS_PWROK can vary across platform. Depending on the platform, the PCH may expect (and wait) for SYS_PWROK at different stages of the boot flow before continuing.

Note: PCH_PWROK and SYS_PWROK both needs to be high to exit reset, but either signal can come up first. PCH does not monitor SYS_PWROK until after PCH_PWROK is asserted. Refer to the [Chapter 45, "Platform Power Sequencing Specification"](#) for details.



36.2.19 Legacy Requirements

- Legacy APWROK implementation has been replaced internally by a timer. PCH will assume any device whose power is controlled by SLP_A#, will ramp within 16ms of SLP_A# de-assertion.
- Legacy timing requirements for DSW_PWROK and RSMRST# based on DSW or Suspend well falling have been removed. Refer to [Chapter 45, "Platform Power Sequencing Specification"](#), Rail to Rail Sequencing Requirements on new guidelines for CFL.

36.2.20 Additional Power Sequencing Considerations

It is possible that on rare occasions, wake events can cause the system to immediately wake after entering in S3 or S4 or other power states. Additionally, similar wake events can occur and cause a system to wake immediately out of Intel ME Mx states (such as Moff).

In such circumstances it is possible that the PCH will generate short duration pulse widths on SLP_S3#, SLP_S4#, SLP_A#, or SLP_SUS#, depending on which system state was being entered. Care should be taken during the platform design to evaluate and account for such events in terms of VR design, power good circuitry design, and overall platform power sequencing in order to ensure timing specifications related to power sequencing are not violated.

To help minimize the impact of such events to platform design and complexity, the PCH has the capability to "stretch" the minimum assertion time on SLP_S3#, SLP_S4#, SLP_A#, and SLP_SUS# signals. Options provided by PCH are shown below.

Table 36-2. Minimum Assertion Time Stretching Options

Signal Name	Units	Minimum Assertion Time Stretching Options
SLP_S3#	seconds	60u, 1m, 50m, 2
SLP_S4#	seconds	1, 2, 3, 4
SLP_A#	seconds	0, 98m, 2, 4
SLP_SUS#	seconds	0, 500m, 1, 4

By default, the stretching capabilities are not enabled by hardware defaults and require the BIOS to set up the features.

A typical configuration recommended by Intel is SLP_S3#= 50 ms, SLP_S4#=1 s, SLP_A#=2 s, SLP_SUS#=4 s. Differences in customer platforms may require or allow for adjustments to these recommendations.

Refer BIOS writer's guide for further details and requirements on programming of these features.

§ §



37

Interrupt Interface Design Guidelines

The interrupt capabilities of the PCH platform maintain support for up to eight PCI interrupt pins and PCI 2.3 Message-Based Interrupts. In addition, the PCH supports system bus interrupt delivery.

37.1 Signal Description

Table 37-1. IOAPIC Interrupt Inputs 16 Through 23 Usage

Number	IOAPIC INTIN PIN	Function in Intel® PCH using the PCI IRQ in IOAPIC
1	IOAPIC INTIN PIN 16 (PIRQA)	USB UHCI Controller 1; USB UHCI Controller 4
2	IOAPIC INTIN PIN 17 (PIRQB)	Option for SMBus
3	IOAPIC INTIN PIN 18 (PIRQC)	USB UHCI Controller 3; SATA Mode
4	IOAPIC INTIN PIN 19 (PIRQD)	USB UHCI Controller 2
5	IOAPIC INTIN PIN 20 (PIRQE)	Internal LAN; option for SCI, TCO, HPET 0,1,2
6	IOAPIC INTIN PIN 21 (PIRQF)	Option for SCI, TCO, HPET 0,1,2
7	IOAPIC INTIN PIN 22 (PIRQG)	Option for SCI, TCO, HPET 0,1,2
8	IOAPIC INTIN PIN 23 (PIRQH)	USB EHCI Controller; option for SCI, TCO, HPET 0,1,2

37.2 Additional Guidelines

37.2.1 PIRQ Routing Example

The following figure shows how PCH uses the PCI IRQ when the I/O APIC is active.

Due to different system configurations, IRQ line routing to the PCI slots ("swizzling") should be made to minimize the sharing of interrupts between both internal Intel PCH functions and PCI functions. The following shows an example of IRQ line routing to the PCI slots.

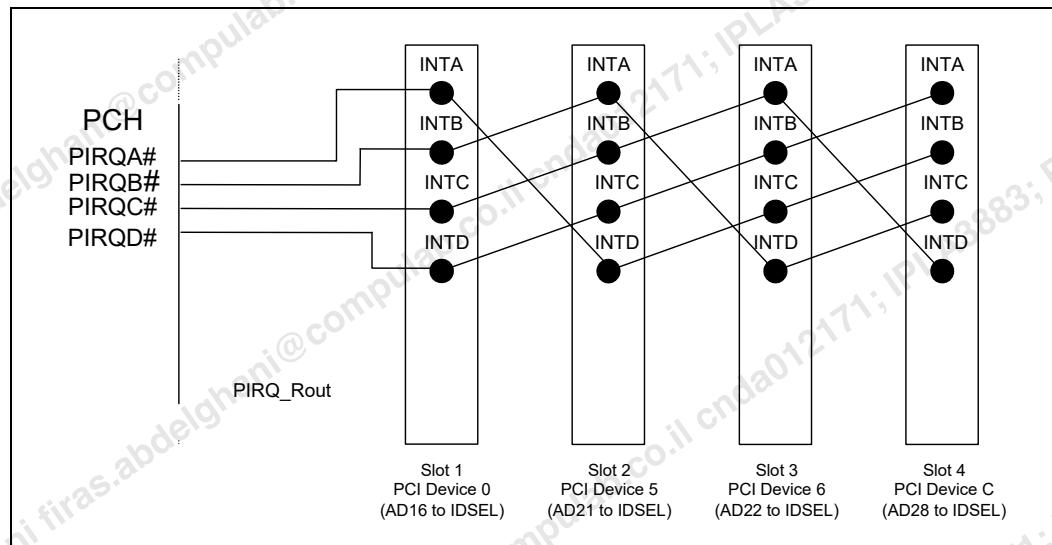
**Figure 37-1. Example PIRQ Routing****Note:**

Figure 37-1 is an example. It is up to each board designer to route these signals in a way that will prove the most efficient for a particular system. A PCI slot can be routed to share interrupts with any of the PCH internal device/functions (but at a higher latency cost).

§ §



38 Critical Low Speed Signals Design Guidelines

Critical Low Speed Signals are identified as critical input signals from the PCH that are low frequency but have huge impact to system functionality or stability. Glitches on these signals may cause the system to behave in an unpredicted manner or cause an unpredicted system shutdown or reset. Although these are low speed signals in nature, glitches may be induced or coupled from nearby high speed signals. Therefore, it is important to keep these signals clean from any potential sources of glitches on the platform.

38.1 Signal Description

38.1.1 Signals Group

Signals listed in [Table 38-1](#) are identified as critical input signals from the PCH that need to be guaranteed glitch free all the time.

Table 38-1. Signals Group (Sheet 1 of 2)

Group	Signal Name	Description
System Management	INTRUDER#	Intruder Detect: This signal can be set to disable system if box detected open.
RTC	SRTCST#	Secondary RTC Reset: This signal resets the manageability register bits in the RTC well when the RTC battery is removed.
RTC	RTCRST#	RTC Reset: When asserted, this signal resets register bits in the RTC well.
Power Management	RSMRST#	Resume Well Reset: This signal is used for resetting the resume power plane logic. This signal must be asserted for at least 10 ms after the suspend power wells are valid. When deasserted, this signal is an indication that the suspend power wells are stable.
Power Management	SYS_RESET#	System Reset: This pin forces an internal reset after being debounced.
Power Management	PWROK	Power OK: When asserted, PWROK is an indication to the PCH that all of its core power rails have been stable for 10 ms. PWROK can be driven asynchronously. When PWROK is negated, the PCH asserts PLTRST#.
Power Management	APWROK	Active Sleep Well Power OK: When asserted, this signal indicates that power to the Intel ME subsystem and integrated LAN are stable.
Power Management	DPWROK	Deep Sleep Well Power OK: When asserted, this signal indicates that power to the DSW are stable.
Power Management	SYS_PWROK	System Power OK: This generic power good input to the PCH is driven and used in a platform-specific manner. SYS_PWROK is used to inform the PCH that power is stable to some other system component(s) and the system is ready to start the exit from reset.
Power Management	PWRBTN#	Power Button: The Power Button will cause SMI# or SCI to indicate a system request to go to a sleep state. If the system is already in a sleep state, this signal will cause a wake event. If PWRBTN# is pressed for more than 4 seconds, this will cause an unconditional transition (power button override) to the S5 state. Override will occur even if the system is in the S1-S4 states. This signal has an internal pull-up resistor and has an internal 16 ms de-bounce on the input.

**Table 38-1. Signals Group (Sheet 2 of 2)**

Group	Signal Name	Description
Power Management	THRMTTRIP#	Thermal Trip: When low, this signal indicates that a thermal trip from the processor occurred, and the PCH will immediately transition to a S5 state. PCH will drive SLP_S3#, SLP_S4# and SLP_S5# low within 1us after sampling THRMTTRIP# active.
Power Management	WAKE#	PCI Express* Wake Event: Sideband wake signal on PCI Express asserted by components requesting wake up.
Processor Interface	RCIN#	Keyboard Controller Reset Processor: The keyboard controller can generate INIT# to the processor. This saves the external OR gate with the processor other sources of INIT#. When the processor detects the assertion of this signal, INIT# is generated for 16 PCI clocks.

38.2 Additional Guidelines

All critical signals must stay away from potential glitch or noise sources on the platform. It is recommended to keep all critical signal traces a minimum of 15 mils away from any clock or high speed differential signals with > 4 V/ns edge rate to avoid glitches from crosstalk.

Table 38-2. Critical Signals Routing Summary

Parameter	Stack-up (MS/SL/DSL)	Units	Routing Recommendation
Spacing	MS/SL/DSL	mils	15 mils

Experiment data shows that certain signals have shown high sensitivity to specific frequencies. Routing those signals near to the frequency source will increase the glitches due to crosstalk. The relationship of each signal with the frequency it is sensitive to is listed in the following table. The designer should try to avoid routing a signal next to the sensitive frequency and the harmonics of its sensitive frequency. If this cannot be avoided, it should be kept a minimal of 15 mils from the respective signal trace.

Table 38-3. Frequency Sensitivity

Signal Name	Frequency to Avoid
INTRUDER#	32 KHz
THRMTTRIP#	125 MHz
RCIN#	33 MHz
APWROK	12.5 MHz
PWRBTN#	32.768 KHz
SYS_RESET#	1 KHz
SYS_PWROK	12.5 MHz
WAKE#	12.5 MHz

§ §



39 M.2 Module

39.1 Overview

M.2 is a versatile form factor that meets the power and thermal needs of add-in cards for ultra-thin profile products like Ultra books™ and Tablets. Further, M.2 also enables the co-existence of multiple I/O technologies on the same module, which is a big benefit for customers that other embedded (small) form factors, like mini PCIe* or mini SATA, are not able to provide.

39.1.1 Reference Specifications

Table 39-1. References

Title	Location
PCI Express* M.2 Specification rev 1.0	http://www.pcisig.com
M.2 Specification in Serial ATA Specification, Revision 3.2	http://www.sata-io.org

39.2 Supported M.2 Features

39.2.1 Connector Keys

Connector keys serve two primary purposes: safety and proper matting guidance.

- **Safety:** A 1:1 definition of the pinout between motherboard and modules to prevent the wrongful insertion of an incompatible module into a wrong slot on the motherboard, including the potential module inversion (i.e. mirroring).
- **Guidance:** Ensures that the pins between the motherboard connector and the module's gold fingers are properly aligned as the module is inserted or extracted. This is especially important when plugging a 1630 Wireless module into the 2230 Socket 1 connector on the motherboard.

39.2.2 Module Stand-off

The location of the stand-off on the motherboard depends on the length of the M.2 modules that the system plans to support. Since the stand-off sub-assembly is meant to be removable (i.e. not soldered down, riveted, etc) it is possible to have multiple holes in the motherboard to accommodate the various modules that may plug into the sockets. CFL supports the following module lengths: 30 mm (Socket 1 applications), 42 mm (Socket 2 applications) and 60 mm (Socket 2 or 3 SSD).

The module stand-off must be connected to ground on the motherboard and module.

The module stand-off serves two primary purposes: Retention and thermal dissipation.

- **Retention:** The retention screw ensures the module is properly secured in place.
- **Thermal dissipation:** With a minimum conductivity requirement of 50 W/m*K (Watts per meter per Kelvin), the retention screw/module stand-off sub-assembly acts as a heat transfer conduit away from the M.2 module. This is particularly important for tight applications where airflow is extremely limited.



39.2.3 Schematics Connector Symbol - Design Considerations

It is recommended, as a good schematics design practice, for the schematics symbol to match the physical connector shape and attributes. The schematics should clearly convey the design intention and should avoid ambiguous symbols. The M.2 specification includes a pinout for the platform and a matching pinout for M.2 modules. Motherboard designers shall use the platform pinout and should document this in the schematics, as a good design practice. The following are examples of bad M.2 connector symbol choices and a well-done M.2 connector schematics symbol.

Refer M.2 specification for pinouts for different interfaces.

Figure 39-1. Poorly-Documented M.2 Connector Schematics Symbols

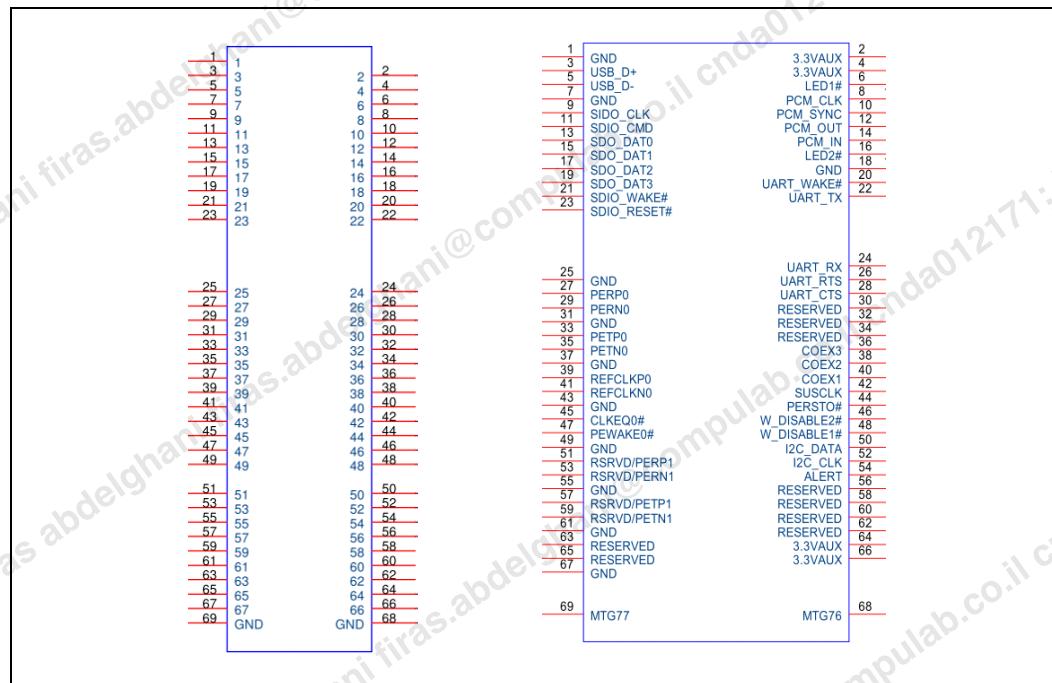


Figure 39-2. Well-Documented M.2 Connector Schematics Symbol


39.3 Design Guidelines for M.2 Interfaces

39.3.1 PCI Express* Interface

Figure 39-3. PCI Express* Interface - Topology

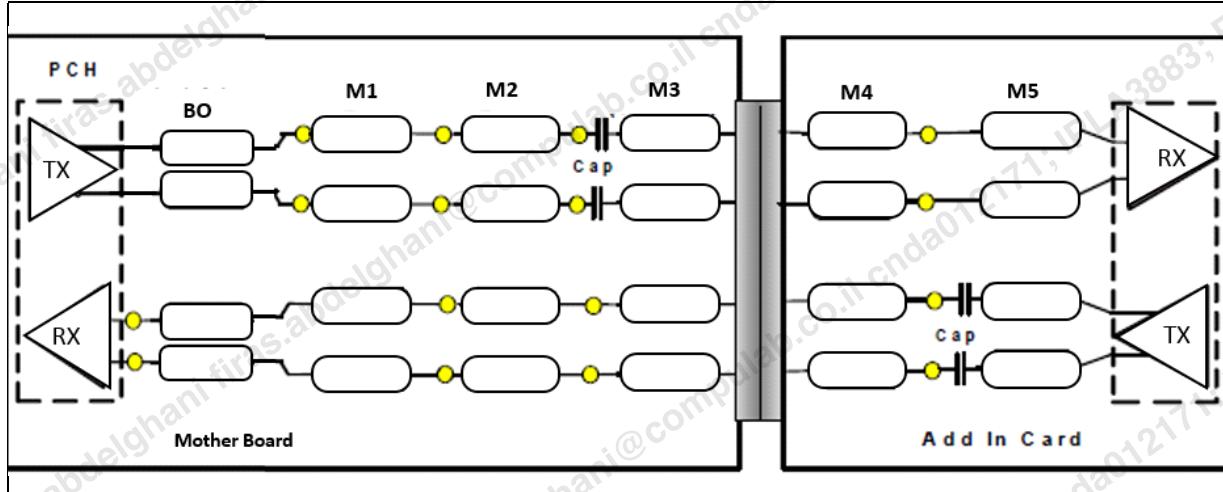


Table 39-2. TX and RX - PCIe Gen1 Layout Guidelines

Segment	T line Type	Reference	Via count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	4	15.2	64 (min) 330 (max)	598.42	2519.68 (min) 12992.13 (max)
				NA		NA	
				8		314.96	
M4+M5	NA	VSS	1	38	38	1496.06	1496.06

Table 39-3. TX and RX - PCIe Gen2 Layout Guidelines

Segment	T line Type	Reference	Via count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	4	15.2	64 (min) 229 (max)	598.42	2519.68 (min) 9015.75 (max)
				NA		NA	
				8		314.96	
M4+M5	NA	VSS	1	38	38	1496.06	1496.06

Table 39-4. TX and RX - PCIe Gen3 Layout Guidelines (Sheet 1 of 2)

Segment	T line Type	Reference	Via Count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	3 (for TX) 2 (for RX)	15.2	64 (min) 203 (max)	598.42	2519.68 (min) 7992.13 (max)
				NA		NA	
				8		314.96	



Table 39-4. TX and RX - PCIe Gen3 Layout Guidelines (Sheet 2 of 2)

Segment	T line Type	Reference	Via Count	Max Length, mm		Max Length, mils	
				Segment	Total	Segment	Total
M4+M5	NA	VSS	1	38	38	1496.06	1496.06

Notes:

- AC Capacitor value
 - Gen1 and Gen2: 75nF --> 265 nF and Gen 2 nominal is 100nF
 - Gen3: 176 --> 265 nF and nominal is 220nF
- Number of Via allowed
 - TX: Gen1 and Gen2 -->4 and Gen3 -->3 (not counting via under package)
 - RX: Gen1 and Gen2 -->4 and Gen3 -->2 (not counting via under package)
 - Express card/Add-in card vias allowed: 1 (for Tx / Rx lanes)
- Breakout length and spacing: An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 -6 mils) is allowed. The total breakout length is still 15.2mm (598.42 mils)
- Reference plane: Continuous Ground Only and Power plane referencing is allowed. Refer to Chapter 3.5.2, Power Referencing tab for guidelines and limitations
- Length Matching between P and N within a differential pair
 - Within same layer mismatch: $\pm 0.254\text{mm}$ ($\pm 10\text{mils}$)
 - Total length mismatch: $\pm 0.127\text{mm}$ ($\pm 5\text{mils}$)
- Length matching between Tx pairs of multiple lanes - If PCIe signals are routed to the same connector (eg a x4 connector), the total delta length between all the TX signals should be within 2". Assuming @ a X4 connector, where TXp/n_0 is shortest length @ 3", while TXp/n_3 is the longest trace, then the longest routing length TXp/n_3 allowed will be 3"+ delta 2" = 5"
- Length matching between Rx pairs of multiple lanes - If PCIe signals are routed to the same connector (eg a x4 connector), the total delta length between all the RX signals should be within 2". Assuming @ a X4 connector, where RXp/n_0 is shortest length @ 3", while RXp/n_3 is the longest trace, then the longest routing length RXp/n_3 allowed will be 3"+ delta 2" = 5"
- Length matching between TX and Rx pairs - If PCIe signals are routed to the same connector (eg a x4 connector), the TX and RX pairs should be length match to be within 2" (see above for length matching TX and RX)
- Include package length in length matching- Not required



39.3.2 SATA Interface

Figure 39-4. SATA Interface - Topology

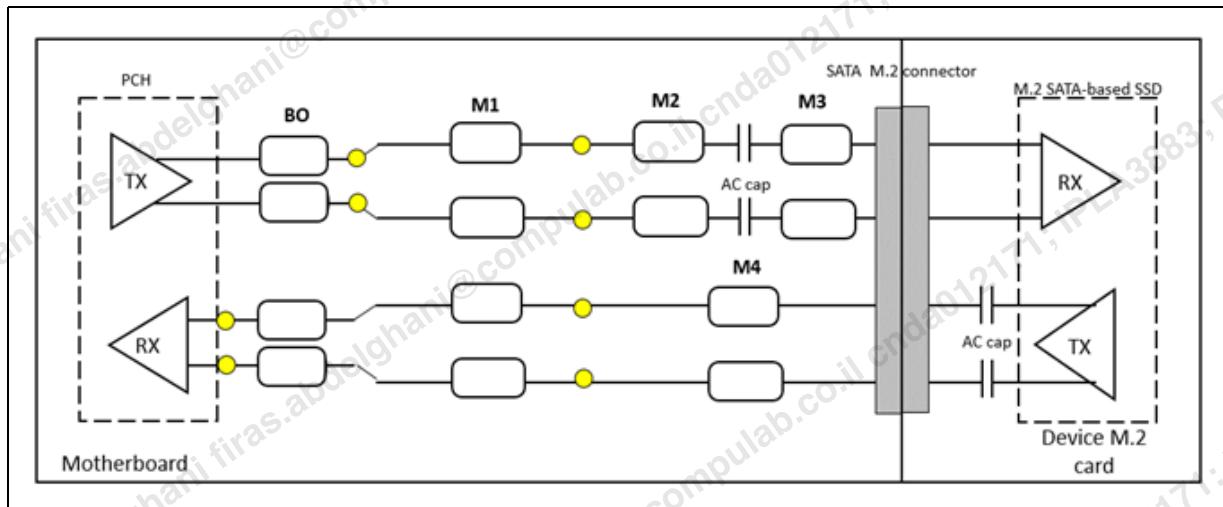


Table 39-5. SATA M.2 Layout Guidelines

Segment	T line Type	Reference	Via count	Max length, mm		Max length, mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	3/2 *	15.2	50.8(min) 178/203.2*(max)	598.42	2000(min) 7007.87/ 8000*(max)
M1	MS/SL/DSL	VSS		NA		NA	
M2	MS	VSS		NA		NA	
M3	MS	VSS		10		393.7	
M4	MS	VSS		M2+M3		M2+M3	

Notes:

- AC Capacitor value: 10nF
- Number of Via allowed
 - 3 vias for 7007.87 mils max length and 2 vias for 8000 mils max length
 - Assumes 1 via in the device M.2 card
- Breakout length and spacing: An initial breakout segment of 4mm (157.48 mils) in length with a tighter pair-to-pair spacing of 0.11mm - 0.16mm (4 - 6 mils) is allowed. The total breakout length is still 15.2mm (598.42 mils)
- Reference plane: Continuous ground only and Power plane referencing is allowed. Refer to Chapter 3.5.2, Power Referencing tab for guidelines and limitations
- Length Matching between P and N within a differential pair
 - Within same layer mismatch: $\pm 0.254\text{mm}$ ($\pm 10\text{mils}$)
 - Total length mismatch: $\pm 0.127\text{mm}$ ($\pm 15\text{mils}$)
- Length matching between TX and Rx pairs - Not required
- Include package length in length matching- Not required



39.3.2.1 AC Capacitor General Guidelines for M.2 SSD Storage Routing on SATA / PCI Express* Multiplexed Ports

The following table summarizes the AC capacitor requirements on the motherboard when using the SATA/PCIe* multiplexed ports.

Note: When SATA and PCIe* are muxed, always route according to SATA design guidelines. SATA does not support signal polarity reversal and does not support lane reversal.

Table 39-6. SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values

Condition	PCI Express* Gen 2 Only	PCI Express* Gen 3 Only	SATA Only	PCI Express* Gen 2 / SATA	PCI Express* Gen 3 / SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ²	None	None ³

Notes:

1. Design Constraint: For PCIe only application, refer to the PCIe guidelines for details.
2. Design Constraint: For SATA only application, both Tx and Rx channels need to have 10 nF capacitors on the motherboard. This option supports all SATA devices. However, the 10 nF capacitor on Rx can be removed if DC coupled ODDs / devices are NOT used.
3. Design Constraint: For PCIe* Gen 2/ SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
4. Design Constraint: For PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
5. Design Constraint: For PCIe* lane that needs to support either **PCIe* Gen2 devices** or **PCIe* Gen3 devices**, follow the PCIe* Gen 3/ SATA multiplexed configuration where the motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**

39.3.3 USB 3.0 Interface (USB3.1 Gen1)

Refer guidelines from [Section 18.1.4.2, "USB 3.1 Gen1 M.2 Topology"](#)

39.3.4 USB 2.0 Interface

Refer guidelines from [Section 19.7.3, "USB 2.0 with M.2 Topology"](#)

39.3.5 SMBus and I²C Topology Guidelines

SMBus: Refer guidelines from [Chapter 27, "SMBus 2.0/SMLink Interface Design Guidelines"](#)

I²C: Refer guidelines from [Chapter 23, "I²C* Interface Design Guidelines,"](#)

39.3.6 UART and SPI Topology Guidelines

UART: Refer guidelines from [Chapter 24, "Universal Asynchronous Receiver Transmitter \(UART\) Interface Design Guidelines"](#)

SPI: Refer guidelines from [Chapter 25, "Generic Serial Peripheral Interface \(GSPI\)"](#)

§ §



40 Front Facing HD/FHD Webcam Design Guidelines

Intel requires 720p cameras in the Ultrabook™ for High Definition Video Conferencing. 720p camera is baseline, but 1080p is recommended by Intel. The guidelines in this chapter are design considerations for designing a Front Facing High Definition (HD) or Full High Definition (FHD) Webcam module. Vendors should reference the (*Platform Product Requirements Document*) for designing the webcam interface in accordance with Intel recommendations.

40.1 Design Considerations

- Customers are recommended to use “Unified” mechanical dimension to enable HD/FHD webcam modules. Use 50 mm (or 100 mm) DMIC spacing for speech/voice program per architecture recommendation.

Figure 40-1. Unified Module Component Placement/Dimension

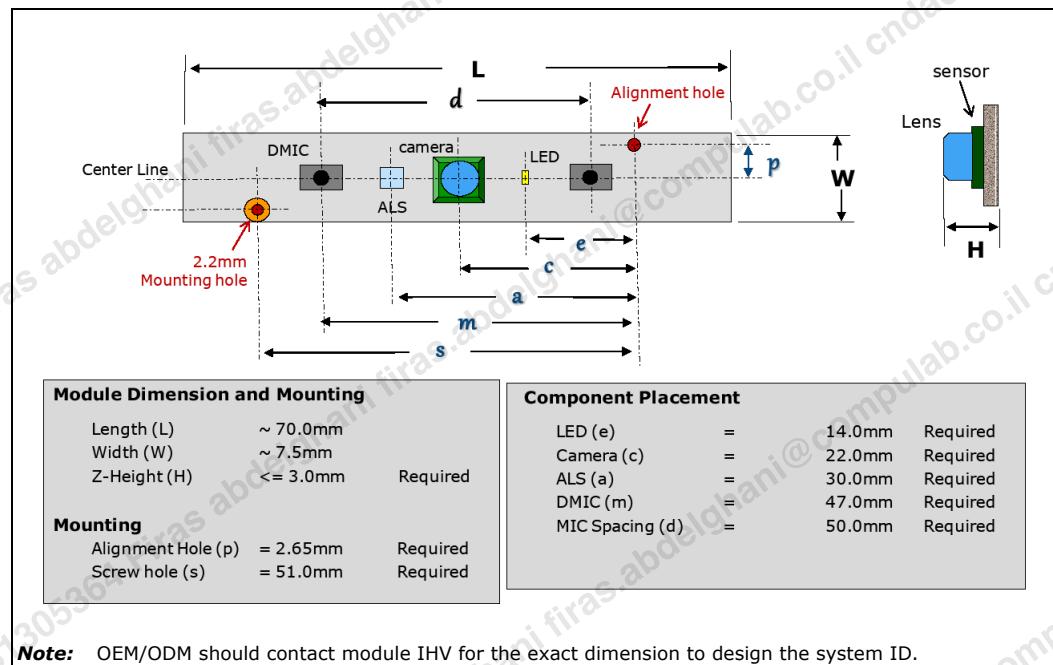


Table 40-1. HD/FHD Webcam Module Connector/Pinout (Sheet 1 of 2)

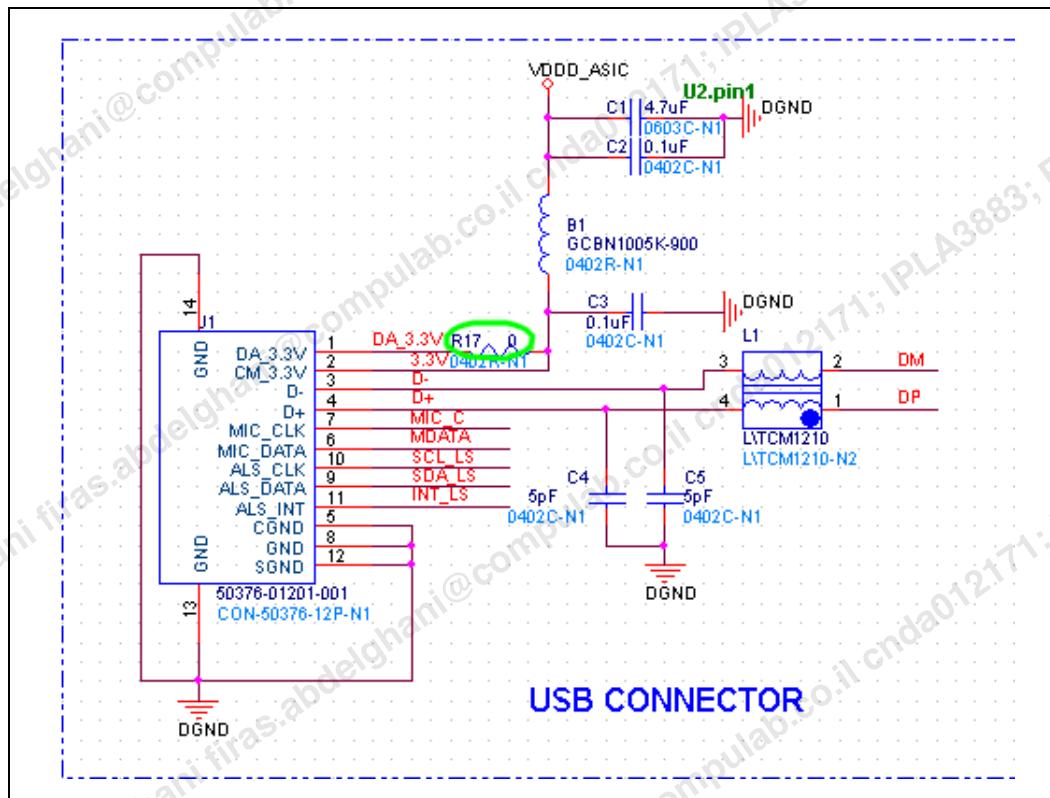
Normal Cam Pin Description			
Pin Number	Name	Pin Type	Function Description
1	DMIC/ALS VCC	Power	Power supply DC +3.3V for DMiC, ALS
2	USB VCC	Power	Power supply DC +3.3V for Camera

**Table 40-1. HD/FHD Webcam Module Connector/Pinout (Sheet 2 of 2)**

Normal Cam Pin Description			
Pin Number	Name	Pin Type	Function Description
3	D-	Data	USB data transmission
4	D+	Data	USB data transmission
5	DGND	Ground	Common Ground
6	MDATA	Output	Microphone Data
7	MCLK	Input	Microphone Clock
8	DGND	Ground	Digital Ground
9	ALS DATA	Output	Ambient Light Sensor Data
10	ALS CLK	Input	Ambient Light Sensor Clock
11	ALS Interrupt	Input	Ambient Light Sensor Interrupt
12	SH GND	Ground	Shielding Ground

Power rail option: Camera has two power sources, one for Camera and second for DMiC and ALS.

- Separated Power rail:
 - Reference design comes with separated power rail option. Camera can be turned on while DMiC and ALS can be turned off for power saving.
- Combined Power rail:
 - Having two separate power rails is not a requirement. OEM/ODM can have a single power rail if they want.
 - If OEMs/ODMs want to merge power for Camera and DMiC and ALS then add a 0-Ω resistor on R17 (Refer Figure 40-2).

Figure 40-2. USB Connector**SS**



41 LAN Design Considerations and Guidelines

The PCH incorporates an integrated 10/100/1000 Mb/s Media Access Controller (MAC) that can be used with an external Intel® Ethernet Connection I219 Physical Layer Transceiver (PHY). Its bus master capabilities enables the component to process high-level commands and perform multiple operations. This can decrease processor use by off loading communication tasks from the processor.

For specific design and implementation information about the I219 Physical Layer Transceiver (PHY), refer the following reference documents.

Table 41-1. Reference Documents

Document	Document Number
Intel® Ethernet Connection I219 (Jacksonville) - Reference Schematic - Rev. 1.0	544767
Intel® Ethernet Connection I219 (Jacksonville) - Cadence Files	NA
Intel® Ethernet Connection I219 (Jacksonville) - Schematic and Layout Checklist - Rev. 1.2	544506
Intel® Ethernet Connection I219 (Jacksonville) - Datasheet - Rev. 2.02	544486
Intel® Network Connections LAN Software Production Version 20.2 v2	560726
Intel® Ethernet Connection I219 [Jacksonville] - Message of the Week (MOW) - 11-Feb-2015	546335
Intel® Ethernet Connection I218/I219 [Clarkville/Jacksonville] - Specification Update - Public - Rev. 1.1	558625

§ §



42

Wireless Connectivity Integration (CNVi) Design Considerations

42.1

Connectivity Integration (CNVi)

CFL-S Rev1.8	<ul style="list-style-type: none"> In section "Jefferson Peak Crystal Input to CNL Topology Routing Guidelines" Updated the block diagram "Jefferson Peak Crystal Input to CNL Topology Diagram"
CFL-H Rev1.6	<ul style="list-style-type: none"> In section "Jefferson Peak Crystal Input to CNL Topology Routing Guidelines" Updated the block diagram "Jefferson Peak Crystal Input to CNL Topology Diagram"
CFL-H Rev 1.8	<ul style="list-style-type: none"> Updated the figure "CNVi Power up Sequence"
CFL-S Rev 1.8	<ul style="list-style-type: none"> Updated the figure "CNVi Power up Sequence"
CFL-H Rev 1.9	<ul style="list-style-type: none"> Updated the table "CNVio M.2 Topology Values"
CFL-S Rev 1.9	<ul style="list-style-type: none"> Updated the table "CNVio M.2 Topology Values"
CFL-S/H date 27/7/18	<ul style="list-style-type: none"> Updated table 42-9 Updated the section "CLKREQ# Timing"
CFL-S/H date 3/7/18	<ul style="list-style-type: none"> Updated table "General guidelines" for BRI/RGI routing guideline section
CFL-S/H date 3/27/19	<ul style="list-style-type: none"> Updated the table "PERST# timing"

Connectivity integration (CNVi) is a general term referring to a family of connectivity solutions which are based on the Pulsar family for CFL. The common component of all these solutions is the Pulsar IP, which is a hard macro embedded in various Intel SoC chips.

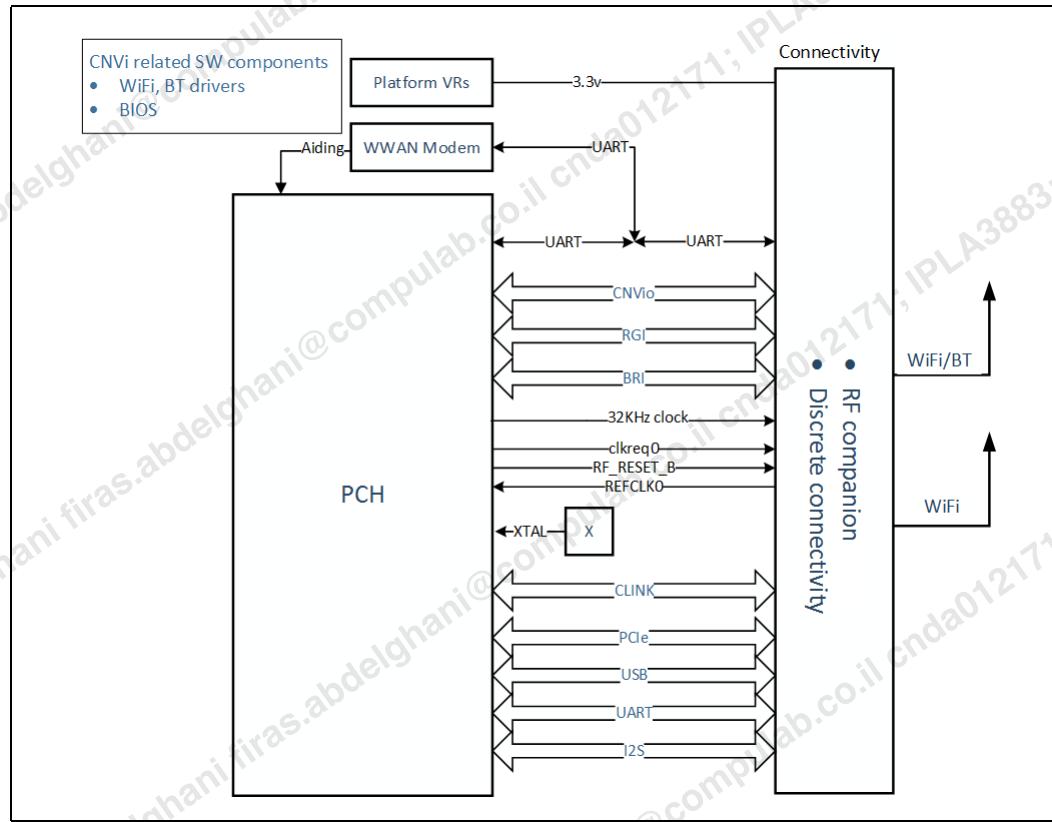
The CNVi solution also contains an external RF companion module (CRF) and RF antennas. This module can be implemented in the following variations:

1. M.2 (2230)
2. Soldered-down M.2 (1216) or
3. Chip-on board (COB).

42.2

Platform High-level Description

Figure below shows the Platform-level view of CNVi, including all related system components.

Figure 42-1. CNVi Platform Block Diagram


The CNVi platform system includes the following blocks:

42.2.1 System-on-Chip (SoC)

Pulsar IP is integrated with PCH (CNP-LP and CNP-H) part of Multi-chip module (MCM).

42.2.2 Platform Crystal

The platform crystal provides reference clock to the SoC. The frequency of this clock varies according to the platform. Possible frequencies for CFL- 24MHz.

42.2.3 WWAN Co-existence

This is a Cellular modem module, typically an M.2 card which provides cellular connectivity to the platform. The WWAN modem interacts with the CNVi through two different interfaces:

- UART- a bus used to exchange Real-Time Co-Existence data between Wi-Fi*/ Bluetooth and the cellular modem.
- Aiding- signals driven by the modem, which are used to assist in improving performance.



42.2.4 Platform VRs

Provides a single 3.3V rail to the external connectivity circuitry.

42.2.5 CNVi Related Straps

These are pin-straps used on SoC pins. These straps control SoC initialization functions related to CNVi implementation.

42.2.6 Connectivity

The connectivity block can have different mechanical implementations depending on the form factor and functionality. Connectivity modules are characterized by the following properties:

- Integration level: Intel RF companion chip or Discrete (Intel or TPV)
- Form factor: M.2 2230 or 1216 or Chip-on-board (COB)
- Wi-Fi* streams: 1x1 or 2x2 802.11ac

42.2.7 Connectivity Antennas

2x2 Configuration include:

- Wi-Fi* Main Antenna
- Shared Wi-Fi*/Bluetooth Antenna (combining Wi-Fi* chain-1 and Bluetooth signals together)

1x1 Configuration include:

- Wi-Fi*/Bluetooth Antenna with Diversity option.

42.3 CNVi Form Factors

The modules described in this section are:

- RF Companion M.2 (2230)
- RF Companion Solder-down M.2 (1216)
- RF Companion COB

42.3.1 RF Companion M.2 (2230)

The RF Companion 2230 module has the same mechanical outline as the standard M.2 connectivity Type 2230-S3-E card.

The standard M.2 Key E connector pin-out is modified to accommodate the proprietary RF companion signals, hence called "Hybrid Key-E". This unique design allows inserting the RF Companion module into a standard M.2 Key E socket.

This feature is only possible when the Motherboard design follows specific guidelines described here.



42.3.1.1 Module Pinout

The RF Companion 2230 module Pinout is shown in Table below.

Table 42-1. RF Companion Module 2230 Pin List (Sheet 1 of 3)

M.2 Pin#	Hybrid Key E M.2 2230 Pin Name	CNVi RF Companion Pin Description	Standard WLAN Solution Pin Description
1	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
2	+V3P3A	Connect all +V3P3A pins to Platform 3.3V supply.	Connect all +V3P3A pins to Platform 3.3V supply.
3	USB D+	Unused	USB
4	+V3P3A	Connect all +V3P3A pins to Platform 3.3V supply.	Connect all +V3P3A pins to Platform 3.3V supply.
5	USB D-	Unused	USB
6	LED1#	Open-drain output capable of driving a platform LED. Optional to connect to Platform LED 1 (if needed).	Open-drain output capable of driving a platform LED. Optional to connect to Platform LED 1 (if needed).
7	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
8	PCM_CLK	Unused	Optional Bluetooth I2S bus clock
9	WGR_D1N	CNVio lane 1 to Pulsar (Negative). Connect to SoC CNVio input D1- pin	Unused
10	PCM_SYNC/LCP_RSTN	RF companion reset signal, active low. Connect to SoC output.	Optional Bluetooth I2S bus sync
11	WGR_D1P	CNVio lane 1 to Pulsar (Positive) Connect to SoC CNVio input D1+ pin	Unused
12	PCM_IN	Unused	Optional Bluetooth I2S bus din
13	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
14	PCM_OUT/CLKREQ0	Clock request signal. Used by the SoC to request the RF companion clock (38.4M Ref clock) for Pulsar and SoC.	Optional Bluetooth I2S bus dout
15	WGR_D0N	CNVio lane 0 to Pulsar (Negative) Connect to SoC CNVio input D0- pin	Unused
16	LED2#	Open-drain output capable of driving a platform LED. Optional to connect to Platform LED 2 (if needed).	Open-drain output capable of driving a platform LED. Optional to connect to Platform LED 1 (if needed).
17	WGR_D0P	CNVio lane 0 to Pulsar (Positive) Connect to SoC CNVio input D0+ pin	Unused
18	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
19	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
20	UART_WAKE#	Unused	Optional host wake for Bluetooth

**Table 42-1. RF Companion Module 2230 Pin List (Sheet 2 of 3)**

M.2 Pin#	Hybrid Key E M.2 2230 Pin Name	CNVi RF Companion Pin Description	Standard WLAN Solution Pin Description
21	WGR_CLKN	CNVio clock to Pulsar (Negative). Connect to SoC CNVio input CLK- pin	Unused
22	UART_RX/BRI_RSP	BRI bus output to SoC. Used for Bluetooth data and control between pulsar and the RF companion. Connect to SoC BRI input.	Optional Bluetooth UART bus rx
23	WGR_CLKP	CNVio clock to Pulsar (Positive) Connect to SoC CNVio input CLK+ pin	Unused
32	UART_TX/RGI_DT	RGI bus input from SoC. Used for general control between pulsar and the RF companion. Connect to SoC RGI output	Optional Bluetooth UART bus tx
33	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
34	UART_CTS/RGI_RSP	RGI bus output to SoC. Used for general control between pulsar and the RF companion. Connect to SoC RGI input	Optional Bluetooth UART bus cts
35	PETP0	Unused	Wi-Fi* PCIe tx lane 0
36	UART_RTS/BRI_DT	BRI bus input from SoC. Used for Bluetooth data and control between pulsar and the RF companion. Connect to SoC BRI output	Optional Bluetooth UART bus rts
37	PETN0	Unused	Wi-Fi* PCIe tx lane 0
38	CLINK_RESET	Unused	CLINK bus reset
39	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
40	CLINK_DATA	Unused	CLINK bus data
41	PERP0	Unused	Wi-Fi* PCIe rx lane 0
42	CLINK_CLK	Unused	CLINK bus clock
43	PERN0	Unused	Wi-Fi* PCIe rx lane 0
44	COEX3	Unused	LTE coex standard pin
45	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
46	COEX2	Unused	LTE coex UART rx
47	REFCLKP0	Unused	Wi-Fi* PCIe clock lane 0
48	COEX1	Unused	LTE coex UART tx
49	REFCLKN0	Unused	Wi-Fi* PCIe clock lane 0
50	SUSCLK	Slow clock input for low power logic. Connect to a 32Khz clock from the Platform or SoC.	Optional Slow clock input for low power logic. Connect to a 32Khz clock from the Platform or SoC. This clock may not be required- depending on the M.2 module specific requirements
51	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
52	PERST0#	Unused	Wi-Fi* PCIe reset lane 0



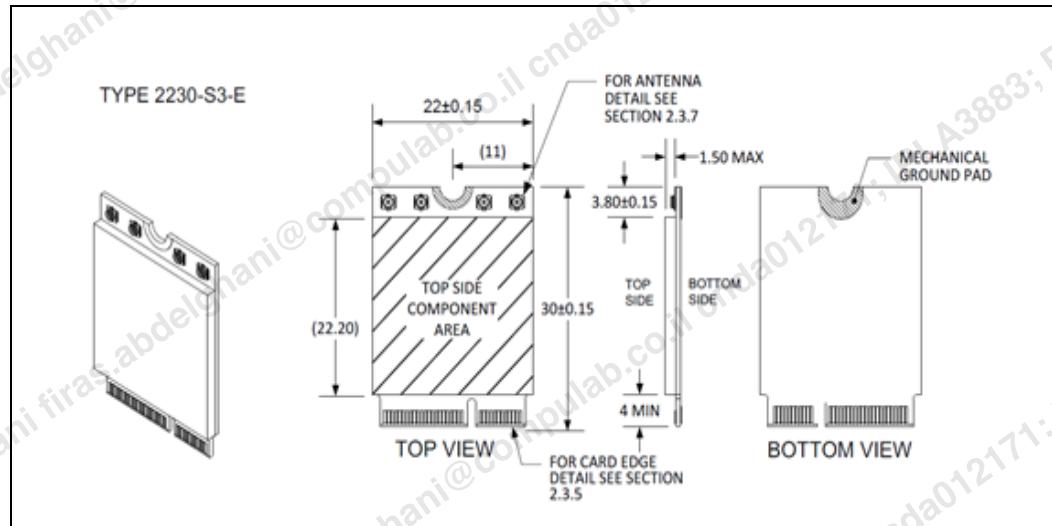
Table 42-1. RF Companion Module 2230 Pin List (Sheet 3 of 3)

M.2 Pin#	Hybrid Key E M.2 2230 Pin Name	CNVi RF Companion Pin Description	Standard WLAN Solution Pin Description
53	CLKREQ0#	Unused	Wi-Fi* PCIe clock request lane 0
54	W_DISABLE2#	BT_KILL input. Optional to connect to a Bluetooth KILL signal from the SoC or from the platform	BT_KILL input. Optional to connect to a Bluetooth KILL signal from the SoC or from the platform
55	PEWAKE0#	Unused	Wi-Fi* PCIe host wake lane 0
56	W_DISABLE1#	WLAN_KILL input. Optional to connect to a Wi-Fi* KILL signal from the SoC or from the platform	WLAN_KILL input. Optional to connect to a Wi-Fi* KILL signal from the SoC or from the platform
57	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
58	A4WP_I2C_DATA	Unused	Unused
59	WT_D1N	CNVio lane 1 from Pulsar (Negative). Connect to SoC CNVio output D1- pin	Unused
60	A4WP_I2C_CLK	Unused	Unused
61	WT_D1P	CNVio lane 1 from Pulsar (Positive) Connect to SoC CNVio output D1+ pin	Unused
62	A4WP_IRQ#	Unused	Unused
63	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
64	REFCLK0	Clock signal. Used The 38.4M ref clock for Pulsar.	Unused
65	WT_D0N	CNVio lane 0 from Pulsar (Negative) Connect to SoC CNVio output D0- pin	Unused
66	PERST1#	Unused	Unused
67	WT_D0P	CNVio lane 0 from Pulsar (Positive) Connect to SoC CNVio output D0+ pin	Unused
68	CLKREQ1#	Unused	Unused
69	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground
70	PEWAKE1#	Unused	Unused
71	WT_CLKN	CNVio clock from Pulsar (Negative). Connect to SoC CNVio output CLK- pin	Unused
72	+V3P3A	Connect all +V3P3A pins to Platform 3.3V supply.	Connect all +V3P3A pins to Platform 3.3V supply.
73	WT_CLKP	CNVio clock from Pulsar (Positive) Connect to SoC CNVio output CLK+ pin	Unused
74	+V3P3A	Connect all +V3P3A pins to Platform 3.3V supply.	Connect all +V3P3A pins to Platform 3.3V supply.
75	GND	Connect all GND pins to Platform ground	Connect all GND pins to Platform ground

42.3.1.2 Module Mechanical Dimensions

The M.2 2230 CRF Module mechanical diagram is shown in figure below.

Figure 42-2. Module Mechanical Diagram - Source is PCI-SIG M.2 Spec Rev 1.0



42.3.1.3 Hybrid Key-E (2230) Pin-Out

The RF Companion M.2 2230 module is intended to be used with a proprietary pin out "Hybrid Key-E" scheme due to the mechanical similarity to a Key-E connector.

The pinout for "Hybrid Key-E" socket on MB is shown in figure below. The CRF signals listed with the prefix "/" signify that they are electrically MUX'd inside the PCH/SoC and are shared.



Figure 42-3. Hybrid Key E'Pinout- Platform Side View

	Standard M.2 Key E	LcP Signals	LcP Signals	Standard M.2 Key E		
74		+V3P3A		GND	75	
72		+V3P3A	WT_CLKP	REFCLKN1	73	
70		PEWake1# (IO)(0/3.3V)	WT_CLKN	REFCLKP1	71	
68		CLKREQ1# (IO)(0/3.3V)		GND	69	
66		PERST1# (O)(0/3.3V)	WT_D0P	PERn1	67	
64	RESERVED	REFCLK0 (I)(1V @38.4MHz)	WT_D0N	PERp1	65	
62	ALERT# (I)(0/1.8)	A4WP IRQ#		GND	63	
60	I2C_CLK (O)(0/1.8V)	A4WP_I2C_CLK	WT_D1P	PETn1	61	
58	I2C_DATA (IO)(0/1.8)	A4WP_I2C_DATA	WT_D1N	PETp1	59	
56		W_DISABLE1# (O)(0/3.3V)		GND	57	
54		W_DISABLE2# (O)(0/3.3V)		PEWake0# (IO)(0/3.3V)	55	
52		PERST0# (O)(0/3.3V)		CLKREQ0# (IO)(0/3.3V)	53	
50	SUSCLK(32kHz) (O)(0/3.3V)	C_P32K (3.3V Tolerant)		GND	51	
48	COEX_TXD (O)(0/1.8V)			REFCLKN0	49	
46	COEX_RXD (O)(0/1.8V)			REFCLKP0	47	
44	COEX3 (IO)(0/1.8V)			GND	45	
42	CLink CLK			PERn0	43	
40	CLink DATA			PERp0	41	
38	CLink RESET (O)(0/3.3V)			GND	39	
36	LPSS UART RTS (O)(0/1.8V) / BRI_DT (MUX'd in PCH/SoC)			PETn0	37	
34	LPSS UART CTS (I)(0/1.8V) / RGI_RSP (MUX'd in PCH/SoC)			PETp0	35	
32	LPSS UART Tx (O)(0/1.8V) / RGI_DT (MUX'd in PCH/SoC)			GND	33	
E	Connector Key			Connector Key		
	Connector Key			Connector Key		
	Connector Key			Connector Key		
	Connector Key			Connector Key	E	
22	LPSS UART Rx (I)(0/1.8V) / BRI_RSP (MUX'd in PCH/SoC)		WGR_CLKP	SDIO Reset#(O)(0/1.8V)	23	
20	UART Wake#(I)(0/3.3V)		WGR_CLKN	SDIO Wake#(I)(0/1.8V)	21	
18	GND	GND/LNA_EN (LcP Production)		GND	SDIO DAT3(I)(0/1.8V)	19
16	LED2# (I)(OD)		WGR_D0P	SDIO DAT2(I)(0/1.8V)	17	
14	PCM_OUT (O)(0/1.8V) / CLKREQ0 (MUX'd in PCH/SoC)		WGR_D0N	SDIO DAT1(I)(0/1.8V)	15	
12	PCM_IN (I)(0/1.8V)		GND	SDIO DAT0(I)(0/1.8V)	13	
10	PCM_SYNC (O)(0/1.8V) / RF_RESET_B (MUX'd in PCH/SoC)		WGR_D1P	SDIO CMD(I)(0/1.8V)	11	
8	PCM_CLK (O)(0/1.8V)		WGR_D1N	SDIO CLK(O)(0/1.8V)	9	
6	LED1# (I)(OD)			GND	7	
4	+V3P3A			USB_D-	5	
2	+V3P3A			USB_D+	3	
				GND	1	

42.3.1.4 Special Considerations for Hybrid Key-E Scheme

The “Hybrid Key-E” scheme relies on assigning multiple functions to M.2 connector pins and to PCH pins. This causes a significant reduction in the amount of signals that needs to be routed between the SoC and the M.2 module.

42.3.1.5 Shared M.2 Socket Pins

The following M.2 pins are shared between different functions:

- PCIe-1/CNVio



These are 6 pins which are assigned to the PCIe-1 bus in the M.2 standard pinout. This bus has 3 differential pairs, two for the PCIe data lanes (one per direction) and one for the PCIe clock. In the "Hybrid Key-E" scheme these signals are used for CNVio interface from Pulsar to the RF companion chip. Due to this sharing, the "Hybrid Key-E" scheme does not support PCIe-1.

- **SDIO/CNVio**

These are 8 pins which are assigned to the SDIO bus in the M.2 standard pinout. This bus has 8 signals, 4 bi-directional for the SDIO data, one bi-directional command signal, one clock (SoC to M.2) and 2 control (Reset SoC to M.2, Wake M.2 to SoC). In the "Hybrid Key-E" scheme these signals are used for CNVio interface the RF companion chip to Pulsar (6 for CNVio and 2 for ground). Due to this sharing, the "Hybrid Key-E" scheme does not support SDIO.

- **PCM/ClockReq and Reset**

The standard M.2 defines 4 pins for a dedicated PCM audio serial bus for Bluetooth. In the "Hybrid Key-E" scheme, two of these signals are used for CNVi Clock (from RF companion to SoC) and Reset (For SoC to RF companion). Since the PCM serial bus is connected to PCH GPIO pins, and the CNVi clock request and reset pins are also connected to PCH GPIO pins, it is possible to have support for both PCM bus and CNVi signals by changing the PCH GPIO multiplexing function select. Due to this sharing, the "Hybrid Key-E" scheme can still support PCM (for discrete Bluetooth connectivity with PCM support).

- **UART (Bluetooth) / BRI and RGI**

The standard M.2 defines 4 pins for a dedicated UART serial bus for Bluetooth. In the "Hybrid Key-E" scheme, all these signals are used for CNVi BRI (Bluetooth Radio Interface) and RGI (Radio Generic interface), each comprising of 2 signals (one per direction). Since the UART serial bus is connected to PCH GPIO pins, and the CNVi BRI, RGI are also connected to PCH GPIO pins, it is possible to have support for both UART bus and CNVi signals by changing the PCH GPIO multiplexing function select. Due to this sharing, the "Hybrid Key-E" scheme can still support Bluetooth UART (for discrete connectivity with BT-UART support).

- **SUSCLK/P_32K**

These signals are both functionally similar. In the M.2 standard this pin is optionally connected to a 32 KHz RTC clock.

- **GND/LNA_EN**

This signal is used for different purposes in CNVi and discrete but in both cases should be connected to ground, therefore it does not affect functionality.

- **A4WP+Ref clock**

In the "Hybrid Key-E" scheme only one of these 4 signals used. This REFCLK0 signal connects the reference clock (single ended, 1V p-p, 38.4MHz) from the RF companion to the SoC. The remaining 3 signals are not used.

- **Non-shared M.2 socket pins**

The functions of these pins impacted by the "Hybrid Key-E" scheme as will be described below:

- **V3P3A, GND**



These are the M.2 card power supply (3.3V) and Ground pins. These pins have the same purpose in either discrete or CNVi implementations and therefore are not affected by the "Hybrid Key-E" scheme.

- **PEWake1#, CLKREQ1#, PERST1#**

These are 3 control signals used by the PCIe-1 bus in standard M.2 cards. Although these signals are not shared with any other function, they have no usage in a "Hybrid Key-E" scheme design. This is because the PCIe-1 bus by itself is not usable (see PCIe-1/CNVio sharing above).

- **PCIe-0 Bus**

This consists of 6 signals (3 differential pairs) used for PCIe data to and from the SoC, and a single pair used for the PCIe bus clock. In a CNVi RF companion these signals are left unused. In standard discrete these signals are being used as the Wi-Fi* bus interface.

- **W_DISABLE1#, W_DISABLE2#,**

These are used for Wi-Fi* and Bluetooth RF-Kill control respectively. Asserting these signals effectively shuts off the RF transmission or the relevant core.

- **PEWake0#, CLKREQ0#, PERST0#**

These are 3 control signals used by the PCIe-0 bus in standard M.2 cards. They should be routed to SoC pins which are assigned to GPIOs in Discrete or Combo modes.

- **Coex UART Interface**

This consist of 3 signals (two UART bus signals and one GPIO) used for Wi-Fi* - LTE coexistence signaling in the M.2 standard definition.

Since these pins are left unused in the RF companion, they can still be used with a discrete M.2 card even when designing with the "Hybrid Key-E" scheme.

In platforms that are designed to support a WWAN modem and "Hybrid Key-E" there should be 3 pins connected to each signal, to allow the modem to connect to the M.2 pin (in the discrete connectivity case) or to the PCH (in the CNVi case). See [Section 42.5.6, "Modem Coexistence 3-way UART Connection"](#) for more details on the UART connection between WWAN, PCH and CNVi.

- **CLINK Interface**

This consist of 3 signals (clock, data and reset). This bus in an Intel proprietary bus. Since these pins are left unused in the RF companion, they can still be used with a discrete M.2 card even when designing with the "Hybrid Key-E" scheme.

- **LED1, LED2**

These are optional pins that are assigned to drive LEDs on the platform in the standard M.2 cards. They are used for the same function when using CNVi and therefore are not affected by the "Hybrid Key-E" scheme.

- **USB Bus**

The standard M.2 defines 2 pins for a differential USB bus. This has no usage in the RF companion.



When using a standard M.2 discrete card, the pins will have the standard functionality and are not affected by the "Hybrid Key-E" scheme. The different connectivity interfaces as used by a discrete connectivity (Standard M.2, Intel connectivity or TPV), CNVi RF companion card are summarized in table below.

Table 42-2. Connectivity Interfaces for Different M.2 2230 Cards

M.2 interface	CNVi	Discrete
PCIe-1	M.2 pins are not connected to the CRF. Wi-Fi* uses internal IOSF to interface the host.	Used for Wi-Fi* host interface
PCIe-2	Not functional Pins are connected to CRF and Pulsar CNVio and can't be used as PCIe.	Not functional Pins are connected to Pulsar CNVio and can't be used as PCIe.
Wi-Fi* SDIO	Not functional Pins are connected to CRF and Pulsar CNVio and can't be used as SDIO.	Not functional Pins are connected to Pulsar CNVio and can't be used as SDIO.
Wi-Fi* CLINK	M.2 pins are not connected to the CRF. Wi-Fi* uses internal CLINK to interface the ME.	Used for Wi-Fi* ME interface
Wi-Fi* RF-Kill	Used (optional)	Used (optional)
Bluetooth USB	M.2 pins are not connected to the CRF. Bluetooth uses internal U2U to interface the host.	Used for Bluetooth USB interface
Bluetooth UART	M.2 pins are not connected to the CRF. Bluetooth uses internal UART to interface the host.	Used for Bluetooth UART interface
Bluetooth I2S (Audio)	M.2 pins are not connected to the CRF. Bluetooth uses internal I2S to interface the host.	Used for Bluetooth I2S interface
Bluetooth wake	M.2 pin is not connected to the CRF. Bluetooth uses internal vGPIO.	Used for Bluetooth wake signal
Bluetooth RF-Kill	Used (optional)	Used (optional)
UART bus to ISH	Pins are connected to Refclock (38.4M system clock). An internal UART is used to connect Pulsar to ISH	Pins are connected to Refclock (38.4M system clock). Can be used for ISH UART connection.
I2C bus to A4WP	Unused.	Unused.
Power supply	Used per M.2 standard	Used per M.2 standard
GND	Used per M.2 standard	Used per M.2 standard

42.3.2 Soldered Down M.2 (SD-1216)

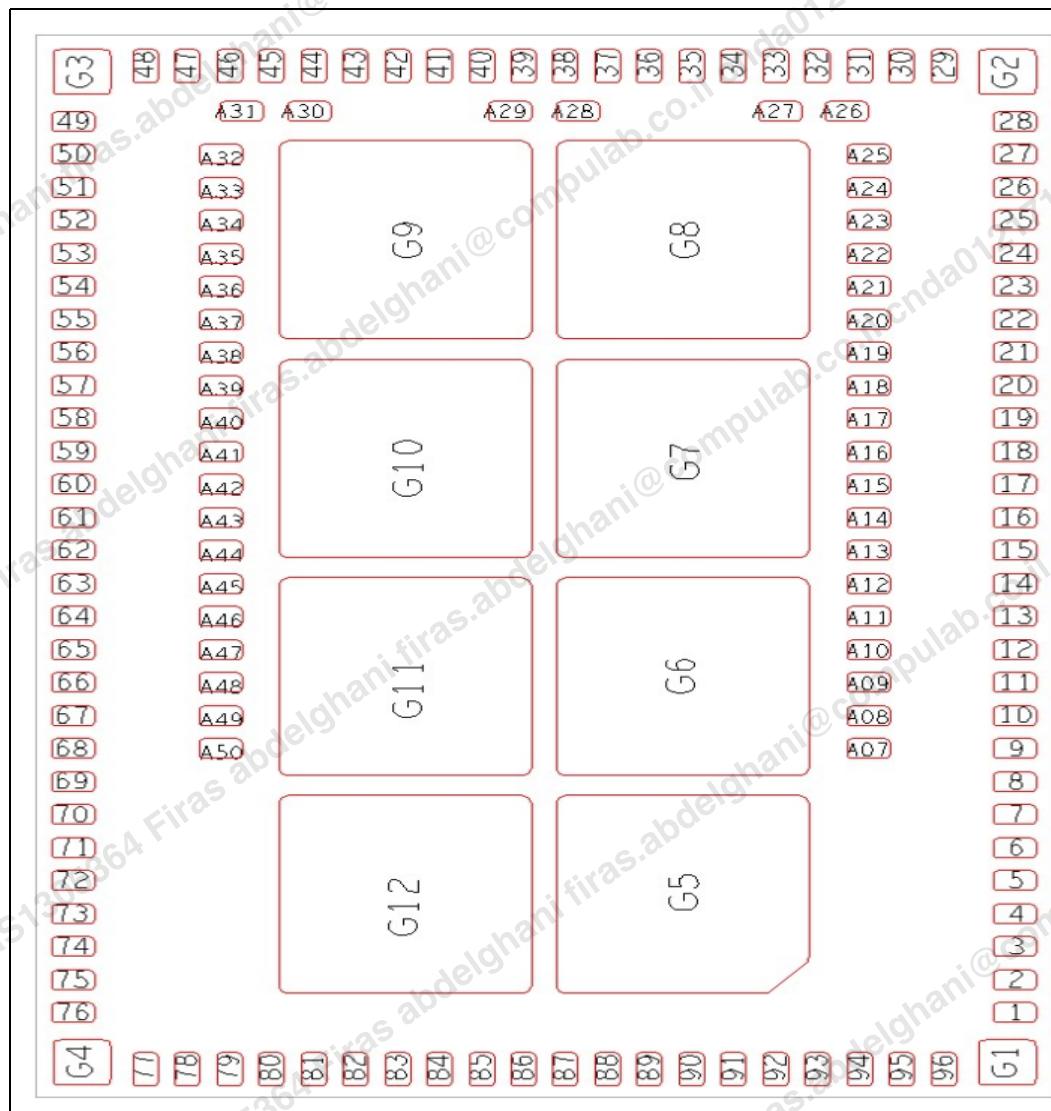
The RF Companion SD-1216 module has the same mechanical outline as the standard M.2 connectivity type 1216-S3. The standard M.2 land pattern is modified to accommodate the proprietary RF Companion Module signals. As opposed to the Connectorized module, the SD-1216 module is not sharing the standard M.2 pads for the RF companion functions. Instead, it has an additional set of solder pads which don't overlap with the standard solder pads. This allows having a single motherboard design that can accommodate either a standard M.2 1216 card or an RF companion 1216 card. However unlike the connectorized case, swapping cards requires removing a soldered

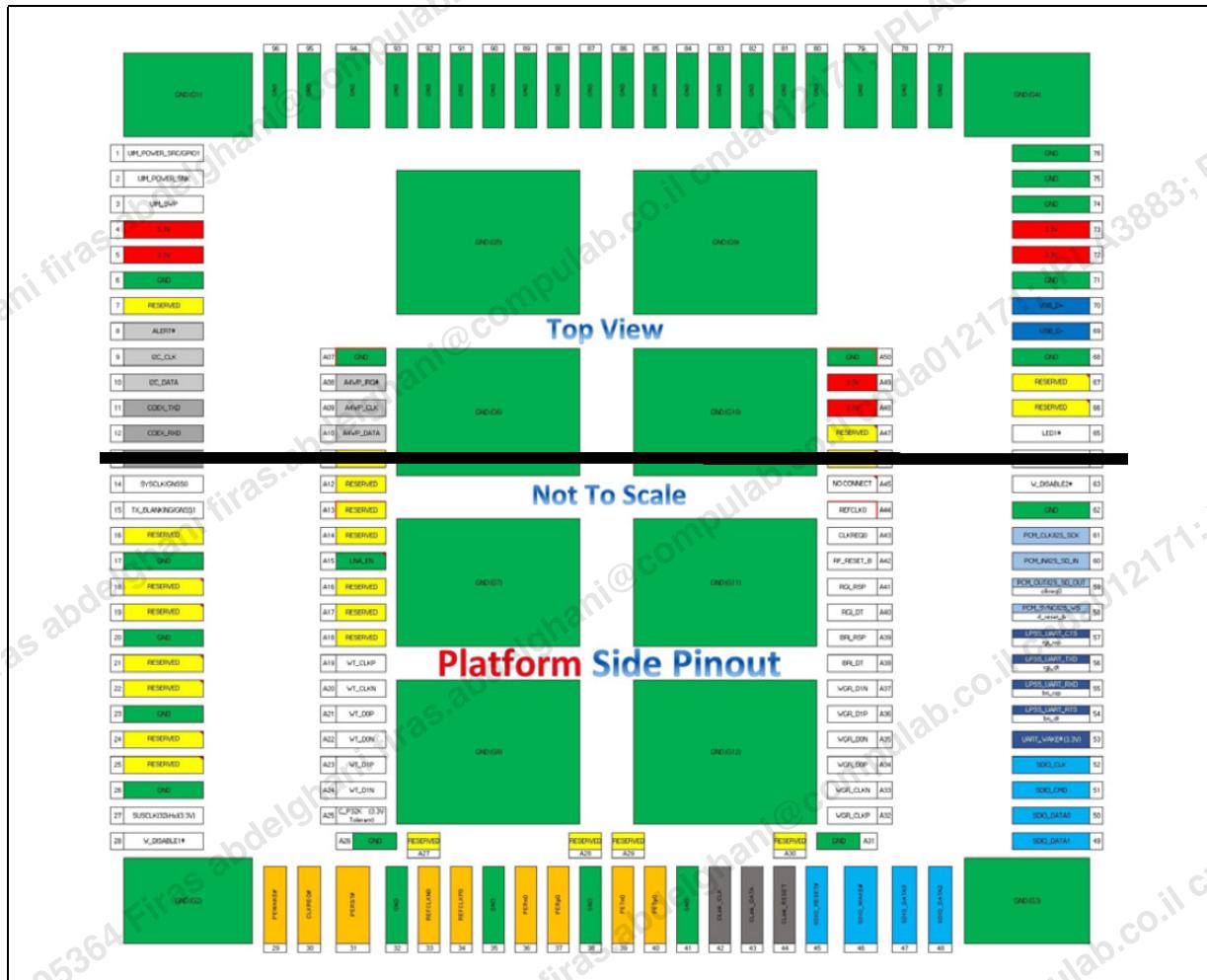
down module and can't be done by a simple socket card exchange. Additionally the assembly tooling and BOM should change between a discrete and CNVi motherboards assembly.

42.3.2.1 Soldered Down 1216 Module Pinout

As explained above, the RF companion module M.2 1216 card has a proprietary set of pads and does no reuse the standard M.2 pads. The special pad-out required for supporting CNVi and discrete on the same motherboard real-estate is shown in Figure below. The corresponding pin-description and CRF signals are shown in [Figure 42-5](#) and [Table 42-3](#) respectively.

Figure 42-4. SD-1216 Module Pad-out for Supporting CNVi and Discrete 1216 Modules



**Figure 42-5. Pin Out Scheme for Dual CNVi/Discrete 1216 Footprint****Table 42-3. RF Companion Module 1216 Pin List (CNVi only) (Sheet 1 of 5)**

Pin #	Pin Name	Function When CNVi is used	Function when Standard M.2 is Used
1	UIM_POWER_SRC/GPIO1	Not used	UIM_POWER_SRC/GPIO1
2	UIM_POWER_SNK	Not used	UIM_POWER_SNK
3	UIM_SWP	Not used	UIM_SWP
4	3.3V	3.3V	3.3V
5	3.3V	3.3V	3.3V
6	GND	GND	GND
7	RESERVED	Not used	RESERVED
8	ALERT#	Not used	ALERT#
9	I2C_CLK	Not used	I2C_CLK
10	I2C_DATA	Not used	I2C_DATA

**Table 42-3. RF Companion Module 1216 Pin List (CNVi only) (Sheet 2 of 5)**

Pin #	Pin Name	Function When CNVi is used	Function when Standard M.2 is Used
11	COEX_TXD	Not used	COEX_TXD
12	COEX_RXD	Not used	COEX_RXD
13	COEX3	Not used	COEX3
14	SYSCLK/GNSS0	Not used	SYSCLK/GNSS0
15	TX_BLANKING/GNSS1	Not used	TX_BLANKING/GNSS1
16	RESERVED	Not used	RESERVED
17	GND	GND	GND
18	RESERVED	Not used	Not used
19	RESERVED	Not used	Not used
20	GND	GND	GND
21	RESERVED	Not used	Not used
22	RESERVED	Not used	Not used
23	GND	GND	GND
24	RESERVED	Not used	Not used
25	RESERVED	Not used	Not used
26	GND	GND	GND
27	SUSCLK(32kHz)(3.3V)	Not used	SUSCLK(32kHz)(3.3V)
28	W_DISABLE1#	W_DISABLE1#	W_DISABLE1#
29	PEWAKE#	Not used	PEWAKE#
30	CLKREQ#	Not used	CLKREQ#
31	PERST#	Not used	PERST#
32	GND	GND	GND
33	REFCLKN0	Not used	REFCLKN0
34	REFCLKP0	Not used	REFCLKP0
35	GND	GND	GND
36	PERn0	Not used	PERn0
37	PERp0	Not used	PERp0
38	GND	GND	GND
39	PETn0	Not used	PETn0
40	PETp0	Not used	PETp0
41	GND	GND	GND
42	CLink_CLK	Not used	CLink_CLK
43	CLink_DATA	Not used	CLink_DATA
44	CLink_RESET	Not used	CLink_RESET
45	SDIO_RESET#	Not used	Not used
46	SDIO_WAKE#	Not used	Not used
47	SDIO_DATA3	Not used	Not used
48	SDIO_DATA2	Not used	Not used
49	SDIO_DATA1	Not used	Not used

**Table 42-3. RF Companion Module 1216 Pin List (CNVi only) (Sheet 3 of 5)**

Pin #	Pin Name	Function When CNVi is used	Function when Standard M.2 is Used
50	SDIO_DATA0	Not used	Not used
51	SDIO_CMD	Not used	Not used
52	SDIO_CLK	Not used	Not used
53	UART_WAKE# (3.3V)	Not used	UART_WAKE# (3.3V)
54	LPSS_UART_RTS/bri_dt	Not used	LPSS_UART_RTS/bri_dt
55	LPSS_UART_RXD/bri_rsp	Not used	LPSS_UART_RXD/bri_rsp
56	LPSS_UART_TXD/rgi_dt	Not used	LPSS_UART_TXD/rgi_dt
57	LPSS_UART_CTS/rgi_rsp	Not used	LPSS_UART_CTS/rgi_rsp
58	PCM_SYNC/I2S_WS	Not used	PCM_SYNC/I2S_WS
59	PCM_OUT/I2S_SD_OUT	Not used	PCM_OUT/I2S_SD_OUT
60	PCM_IN/I2S_SD_IN	Not used	PCM_IN/I2S_SD_IN
61	PCM_CLK/I2S_SCK	Not used	PCM_CLK/I2S_SCK
62	GND	GND	GND
63	W_DISABLE2#	W_DISABLE2#	W_DISABLE2#
64	LED2#	LED2#	LED2#
65	LED1#	LED1#	LED1#
66	RESERVED	Not used	RESERVED
67	RESERVED	Not used	RESERVED
68	GND	GND	GND
69	USB_D-	Not used	USB_D-
70	USB_D+	Not used	USB_D+
71	GND	GND	GND
72	3.3V	3.3V	3.3V
73	3.3V	3.3V	3.3V
74	GND	GND	GND
75	GND	GND	GND
76	GND	GND	GND
77	GND	GND	GND
78	GND	GND	GND
79	GND	GND	GND
80	GND	GND	GND
81	GND	GND	GND
82	GND	GND	GND
83	GND	GND	GND
84	GND	GND	GND
85	GND	GND	GND

**Table 42-3. RF Companion Module 1216 Pin List (CNVi only) (Sheet 4 of 5)**

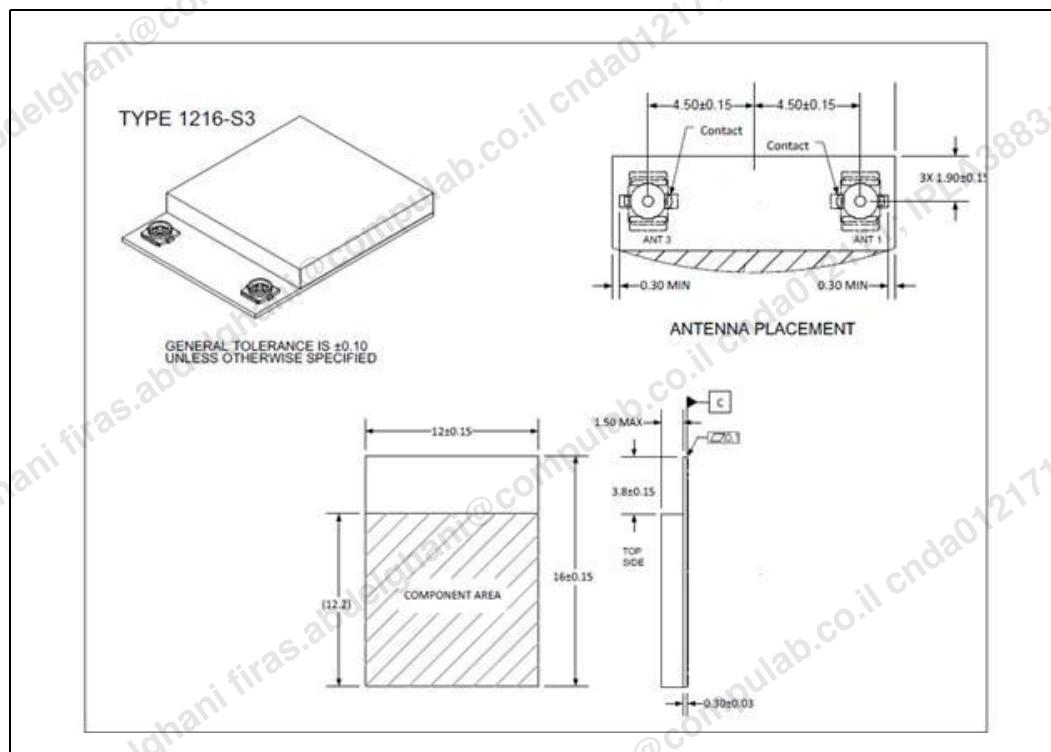
Pin #	Pin Name	Function When CNVi is used	Function when Standard M.2 is Used
86	GND	GND	GND
87	GND	GND	GND
88	GND	GND	GND
89	GND	GND	GND
90	GND	GND	GND
91	GND	GND	GND
92	GND	GND	GND
93	GND	GND	GND
94	GND	GND	GND
95	GND	GND	GND
96	GND	GND	GND
G1	GND	GND	GND
G2	GND	GND	GND
G3	GND	GND	GND
G4	GND	GND	GND
G5	GND	GND	GND
G6	GND	GND	GND
G7	GND	GND	GND
G8	GND	GND	GND
G9	GND	GND	GND
G10	GND	GND	GND
G11	GND	GND	GND
G12	GND	GND	GND
A07	GND	GND	Not Applicable
A08	A4WP_IRQ#	A4WP_IRQ#	Not Applicable
A09	A4WP_CLK	A4WP_CLK	Not Applicable
A10	A4WP_DATA	A4WP_DATA	Not Applicable
A11	RESERVED	RESERVED	Not Applicable
A12	RESERVED	RESERVED	Not Applicable
A13	RESERVED	RESERVED	Not Applicable
A14	RESERVED	RESERVED	Not Applicable
A15	LNA_EN	GND	Not Applicable
A16	RESERVED	RESERVED	Not Applicable
A17	RESERVED	RESERVED	Not Applicable
A18	RESERVED	RESERVED	Not Applicable
A19	WT_CLKP	WT_CLKP	Not Applicable
A20	WT_CLKN	WT_CLKN	Not Applicable
A21	WT_DOP	WT_DOP	Not Applicable

**Table 42-3. RF Companion Module 1216 Pin List (CNVi only) (Sheet 5 of 5)**

Pin #	Pin Name	Function When CNVi is used	Function when Standard M.2 is Used
A22	WT_D0N	WT_D0N	Not Applicable
A23	WT_D1P	WT_D1P	Not Applicable
A24	WT_D1N	WT_D1N	Not Applicable
A25	C_P32K	C_P32K	Not Applicable
A26	GND	GND	Not Applicable
A27	RESERVED	RESERVED	Not Applicable
A28	RESERVED	RESERVED	Not Applicable
A29	RESERVED	RESERVED	Not Applicable
A30	RESERVED	RESERVED	Not Applicable
A31	GND	GND	Not Applicable
A32	WGR_CLKP	WGR_CLKP	Not Applicable
A33	WGR_CLKN	WGR_CLKN	Not Applicable
A34	WGR_D0P	WGR_D0P	Not Applicable
A35	WGR_D0N	WGR_D0N	Not Applicable
A36	WGR_D1P	WGR_D1P	Not Applicable
A37	WGR_D1N	WGR_D1N	Not Applicable
A38	BRI_DT	BRI_DT	Not Applicable
A39	BRI_RSP	BRI_RSP	Not Applicable
A40	RGI_DT	RGI_DT	Not Applicable
A41	RGI_RSP	RGI_RSP	Not Applicable
A42	RF_RESET_B	RF_RESET_B	Not Applicable
A43	CLKREQ0	CLKREQ0	Not Applicable
A44	REFCLK0	REFCLK0	Not Applicable
A45	NO CONNECT	NO CONNECT	Not Applicable
A46	RESERVED	RESERVED	Not Applicable
A47	RESERVED	RESERVED	Not Applicable
A48	3.3V	3.3V	Not Applicable
A49	3.3V	3.3V	Not Applicable
A50	GND	GND	Not Applicable

42.3.2.2 Soldered Down 1216 Module Mechanical Dimensions

Figure 42-6. 1216 Module Mechanical Diagram

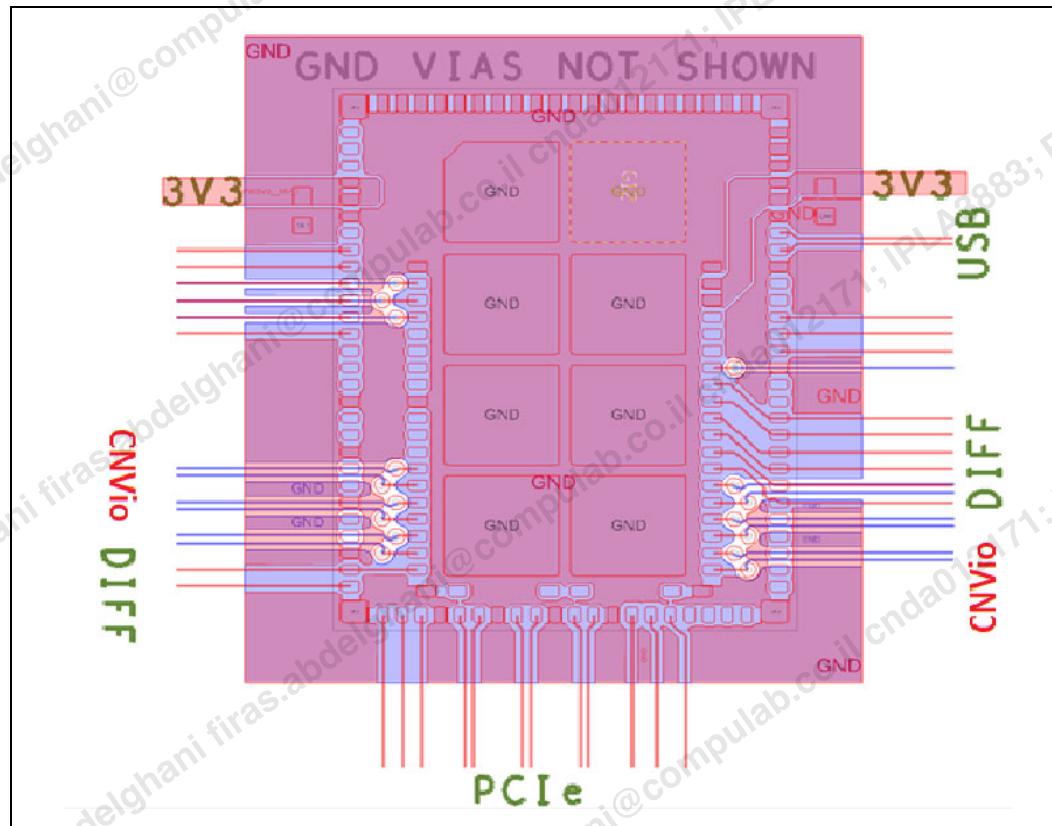


42.3.2.3 Breakout Example for JfP Soldered Down Module

The soldered down JfP module has a special pad shape which combines the standard M.2 pad ring on the outside with the new inner ring of the CNVi pads. It is recommended to consider all signal properties when designing the motherboard for dual discrete/CNVi design supporting Jefferson Peak 1216. An example for the breakout layout for a type-3 board (with no micro-via) is shown in the figure below.

Note:

In order to keep the picture clear, this example shows only 2 signal layers (top layer and 3'rd layer) while the other layers are not shown. Also there is an assumption that the second layer shall be ground.

Figure 42-7. Board Layout Example Showing Breakout from JfP 1216 pads

42.4 Platform Considerations

42.4.1 Selecting Connectivity Solution

The platform motherboard can be designed to support discrete connectivity (either Intel or TPV), integrated connectivity (CNVi).

Note:

All CNVi 2230 SKUs can support a "Hybrid Key-E" routing with no jumpers. When considering a TPV module one should only use a Key-E module if the motherboard design is "Hybrid Key-E". A Key-A module will not fit into this scheme.

Table 42-4. CNVi Module SKUs (Sheet 1 of 2)

SKU	M.2 type	Wi-Fi* chains	LTE coex (on-module BAW filter)	Comments
JfP1 2230	2230	1x1	No	Basic 1x1
JfP1 2230 diversity	2230	1x1	No	Basic 1x1 with diversity
JfP1-SD	1216	1x1	No	Solder-down 1x1

**Table 42-4. CNVi Module SKUs (Sheet 2 of 2)**

SKU	M.2 type	Wi-Fi* chains	LTE coex (on-module BAW filter)	Comments
JfP1-SD diversity	1216	1x1	No	Solder-down 1x1 with diversity
JfP2 2230	2230	2x2	No	Basic 2x2
JfP2 2230 vPro	2230	2x2	No	vPro 2x2
JfP2 2230 vPro Coex	2230	2x2	Yes	vPro 2x2 with Coex
JfP2 SD	1216	2x2	No	Solder-down 2x2
JfP2 SD Coex	1216	2x2	Yes	Solder-down 2x2 with LTE Coex
JfP2 SD vPro	1216	2x2	No	Solder-down vPro 2x2

Table 42-5. Intel Discrete Module SKUs

SKU	M.2 type	Wi-Fi* chains	LTE coex (on-module BAW filter)	Comments
ThP2 2230	2230	2x2	No	Basic 2x2 module
ThP2 2230 vPro	2230	2x2	No	vPro 2x2 module

42.4.2 CNVi Reference Clock

The two configurations related to having a M.2 discrete or CNVi (with no clock sharing) is shown in [Figure 42-8, “CNVi Clock Connections”](#) and [Figure 42-9, “Discrete Clock Connections”](#) respectively.

Figure 42-8. CNVi Clock Connections

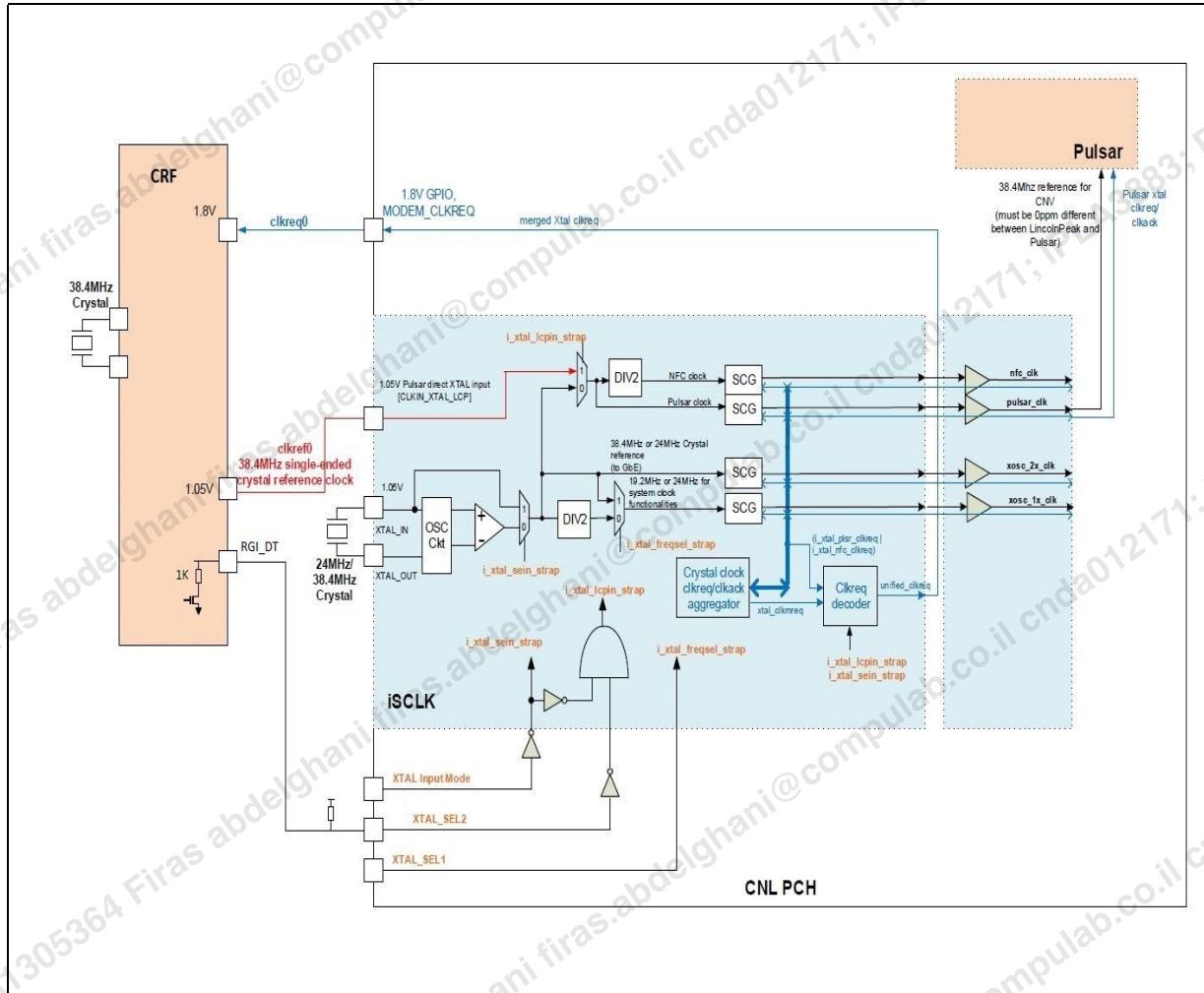
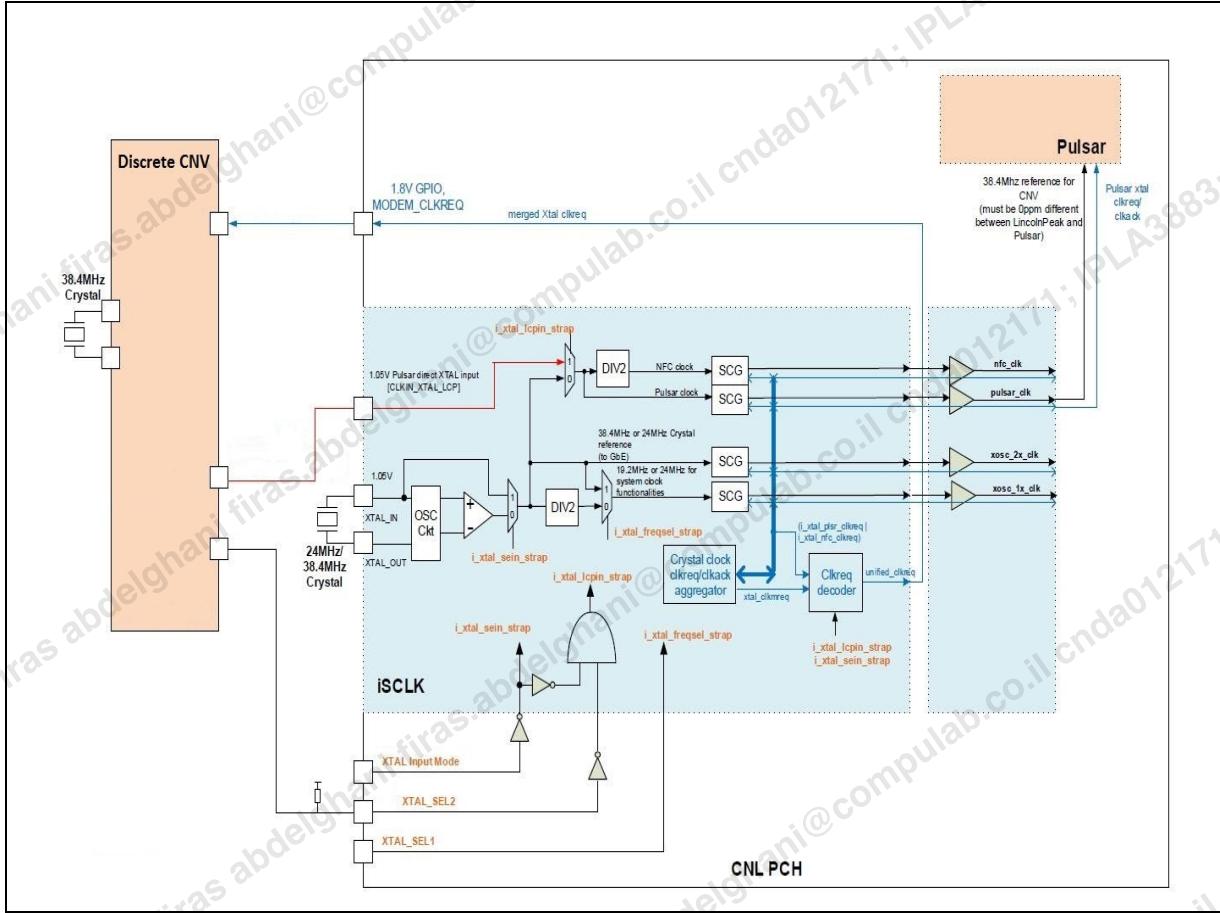


Figure 42-9. Discrete Clock Connections


42.4.2.1 SoC Pin-straps Configurations Related to CNVi and Clock Sharing

An SoC that supports CNVi has special interfaces and configurations that needs to be set properly even if the platform is not using integrated connectivity (CNVi).

Pin Straps

These are SoC pins which are used at power-up to determine whether an RF companion exists or not. Based on this information the PCH will determine how to run the boot flow and how to configure internal logic that has different behavior when using M.2 discrete versus CNVi.

For CFL platform with CNP PCH, the SoC uses the RGI_DT signal to drive this pin strap. The property of this signal is that it is connected to a strong pull-down resistor at the time of CRF power up. Based on this property, with an additional SoC pull-up resistor on this GPIO pin, the CNVi/discrete option can be resolved. Refer to [Table 42-6](#) for the details of the SoC straps for PCH.

**Note:**

CNVi RGI_DT pin gets the pull-down resistor (1K ohm) from the internal CRF module when CNVi is enabled. There must not be any pull-down resistor connected on the board.

PCH Main Clock Source

Alternatively, the CFL SoC shall be configured to have 2 clocks: One for the Pulsar IP and another one for the rest of the PCH circuitry. When CNVi is not used, the main clock source for the PCH is the PCH main crystal clock.

Table 42-6. SoC Straps Related to CNVi and Clock Sharing

SoC	Configuration	XTAL input mode	XTAL input freq (XTAL_SEL1)	XTAL_SEL2	SoC clock source
CNL (CNP PCH)	CNVi Mode	Disconnected Pulled up internally	Pulled up for 24M	Pulled down by an internal resistor (1K ohm) within the CRF module via CNVi RGI_DT pin	SoC crystal oscillator. A 24M XTAL_IN and XTAL_OUT
	Discrete Mode	Disconnected Pulled up internally		Pulled up by an external resistor (20K ohm) and by Discrete UART0_RXD pin	

42.4.3 SoC RCOMP Pin Connection

The RCOMP pin is a SoC pin which is connected to a calibration resistor. This pin is used for interfacing an internal calibration circuit used for the CNVio bus. When the CNVio bus goes out of power up, Pulsar will run a self-calibration sequence which will result in calibrating the CNVio ports to the desired impedance. The RCOM resistance value shall be set to 150 ohm within 1% accuracy.

42.4.4 RF-Kill and LED Support

In legacy platforms, the RF-Kill and LED features are used to control the Wi-Fi* and Bluetooth operation (RF-Kill) and indicate Wireless link status (LED).

The traditional motherboard design has both functions built with direct connection between the connectivity card (M.2 pins) and discrete platform components (e.g. Laser Emitting Diodes for LED and pushbutton switches for RF-Kill).

In newer platforms these functions can be supported in various different methods including SW control. To maintain compatibility to legacy motherboard designs, the CRF is designed with RF-Kill and LED support.

The following limitations should be considered if RF-Kill or LED legacy support is required for a specific platform design:

- RF-Kill and LED pins for a JfP(2x2) and ThP (Discrete) modules (either 2230 or 1216) use dedicated pins of the CRF chip and are connected to the standard M.2 pins dedicated to these functions namely:
 - W_DISABLE2# for Bluetooth RF-Kill
 - W_DISABLE1# for Wi-Fi* RF-Kill



In some cases the platform design is required to have an explicit Wi-Fi* and Bluetooth disable function in BIOS to completely shut down Wi-Fi* and Bluetooth even when the connectivity module HW is connected on the board. To support this design, the M.2 W_DISABLE# pins should be routed to SoC GPIOs and forced to a logical zero by BIOS for disabling the Wi-Fi* and Bluetooth completely.

42.4.5 CLINK Support

For CNVi CLINK is internal to the PCH and does not need an connection. In order to support CLINK with discrete M.2 modules (such as Thunder Peak) connect the CLINK to the CLINK pins of the M.2 connector.

42.4.6 CNVi Power Supply Connections

Integrated connectivity (CNVi) power delivery has two parts:

- The integrated part- which is directly connected to the SoC power delivery
- The external part- which is similar to the standard M.2 power supply scheme

The integrated part of CNVi relays on the PCH power rails and therefore no additional routing or power budgeting is required beyond the PCH recommended design.

[Figure 42-10](#) provides information on the pin connections which control power delivery to CNVi IP inside PCH. To complete the picture this figure also shows the M.2 module power supply pins (Note: These are the same for either a standard M.2 module or a CRF).

Note that the PCH-H contains an internal 1.8V linear regulator that is capable of powering the VCCPRIM1P8 rail without adding a 1.8V voltage regulator to the platform. Therefore there are 2 optional configurations:

- Platform supplies the 1.8V rail directly
- 1.8V rail is power by the PCH internal 1.8V LDO

The two options has different connection scheme at the platform level which is shown in [Figure 42-10](#) and [Figure 42-11](#) below.

The power delivery is the same for a CNVi only design and for a CNVi/Discrete (dual) design.

In some designs, the connectivity solution is powered by a power switch which allows the PCH to dynamically control the 3.3V supply to the M.2 card. This is done in the PCH by using a signal called SLP_WLAN# (active low) to control a power switch on the motherboard which feeds the M.2 supply pins.

When designing the platform for CNVi, it is recommended to either not have this switch in the design, or hardware it to be always-on by following PCH. This is because the operation of the RF companion module does not allow switching off its main power in any system state that the PCH is powered on, in order to keeping synchronization with PCH all the time.

Refer to the technical white-paper (RDC#573970) related to the correct usage of Load Switch.

Note that the power supply to the M.2 module is connected directly to the platform V3.3A rail without having any controlled power switch on the line. This ensures that the CNVi will be powered early in the platform power up process as required by the CNVi power up sequencing. Note that CNVi does not support wake on WLAN/BT during deep system sleep states (DSx). Connecting the CRF to 3.3V_DSW rail is not recommended since the PCH rails needed for CNVi will be powered off in deep system sleep state, getting out of DSx requires the CNVi, in the PCH, to Boot, Cold-Boot, in any case so no real value to have the CRF on 3.3V_DSW.

Figure 42-10.CNVi Power Connections with 1.8V Platform VR

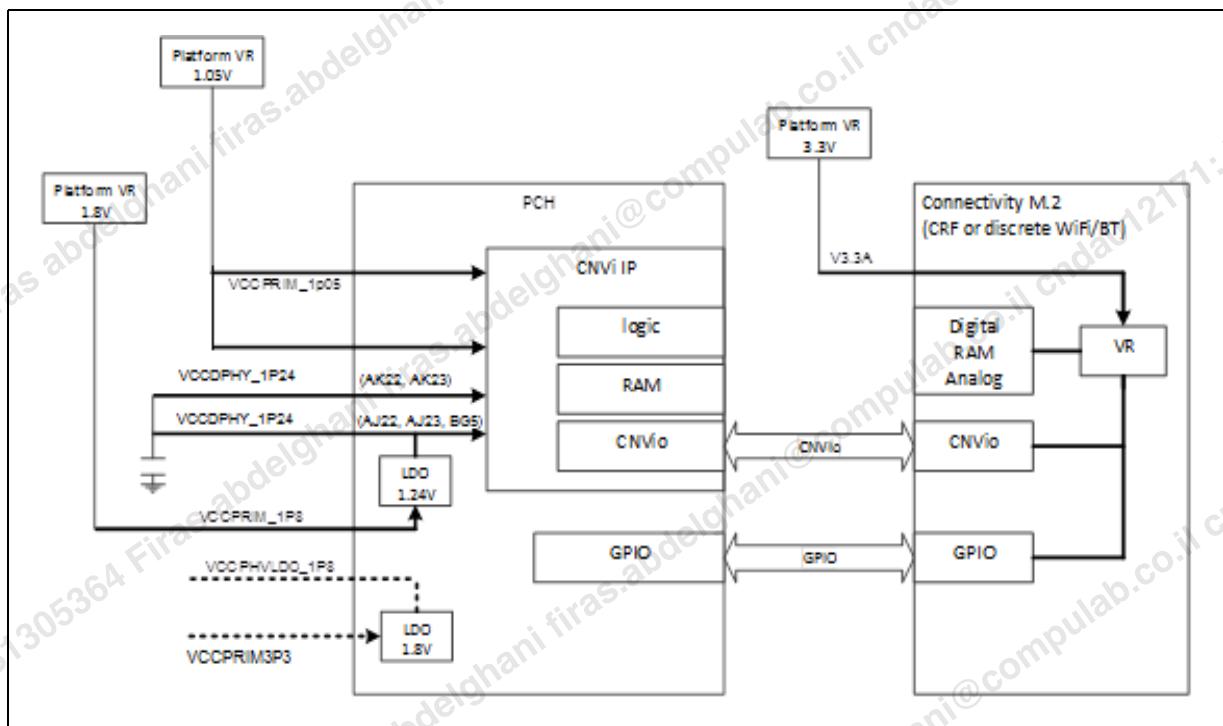
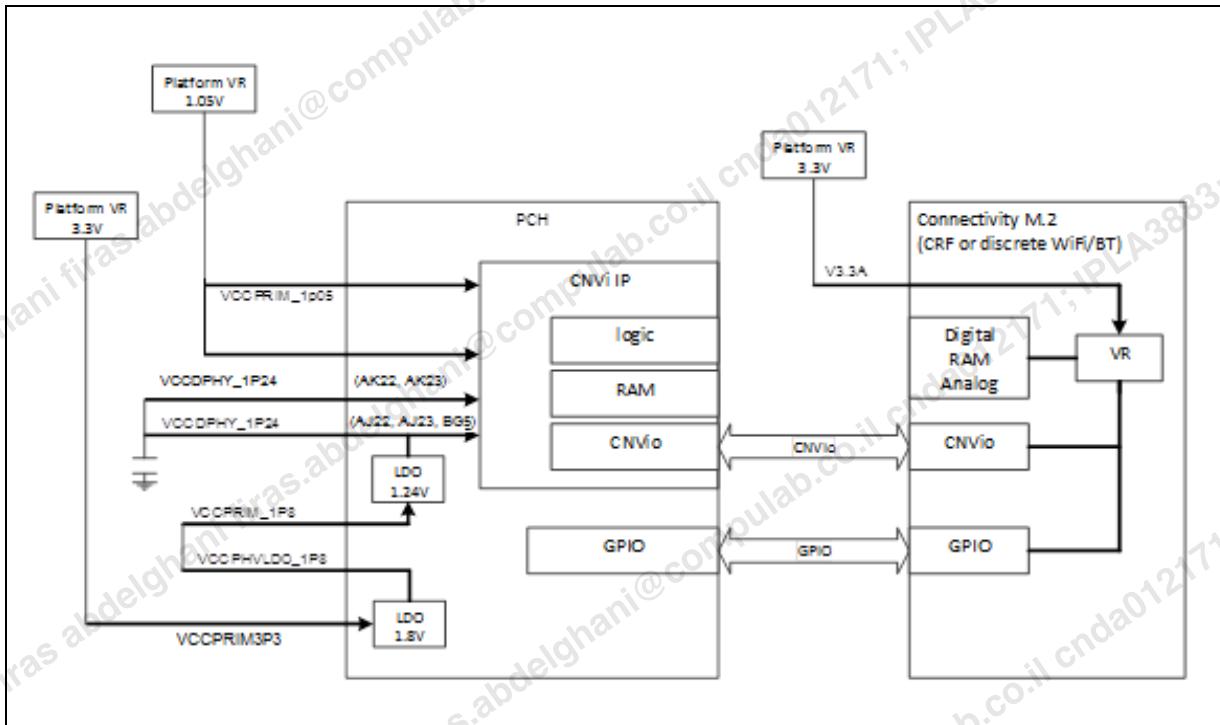


Figure 42-11.CNVi Power Connections with Internal 1.8V LDO

Note:

When CNVi is not used in the design:

- VCCDPHY_1P24 (balls AK22, AK23) pin shall be disconnected from the VCCDPHY_1P24 (AJ22, AJ23, BG5) pin.
- The decoupling capacitor shall remain connected to the VCCDPHY_1P24 (AJ22, AJ23, BG5) pin.

Notes:

1. Refer to the technical advisory (RDC#574860) related to the usage of internal LDO
2. Refer to the technical white-paper (RDC#573970) related to the usage of Load Switch

42.4.7 Electrical Specifications for CNVi 1.8V Signals

For using GPP_D bank signals for CNVi, the input voltage to the VCCPGPPD pin must be set to 1.8V.

The below diagrams illustrate the detailed electrical requirements for the 1.8V CNVi signals:

Table 42-7. Input/Output Electrical Specifications



I/O Type	Symbol	Parameter	Min	Max	Unit	Notes
1.8V I/O RF_RESET_B	V_{IH}	Input High Voltage	1.26	2.1	V	
	V_{IL}	Input Low Voltage	-0.3	0.54	V	
	$R_{PU/PD}$	Weak Pull-Up or Pull-Down	70	150	Kohm	
	I_{IN}	Input Leakage Current		10	uA	No Pull Up/ Down
	V_{OH}	Output High Voltage	1.62	1.8	V	$I_o = 2mA$ Load = 20pF
	V_{OL}	Output Low Voltage	0	0.18		$I_o = 2mA$ Load = 20pF
	T_R, T_F	Rise, Fall Time		6	ns	Load = 20pF
	C_{IO}	IO Pin Capacitance		2	pF	
1.8V FS I/O A4WP_IRQ# A4WP_I2C_CLK A4WP_I2C_CLK (Note 1)	V_{IH}	Input High Voltage	1.26	2.1	V	
	V_{IL}	Input Low Voltage	-0.3	0.54	V	
	$R_{PU/PD}$	Weak Pull-Up or Pull-Down	100	180	Kohm	
	I_{IN}	Input Leakage Current		10	uA	No Pulls
	V_{OL} Push-Pull	Output Low Voltage Push-pull	0	0.36		$I_o = 2mA$ Load = 50pF
	V_{OH} Push-Pull	Output High Voltage Push-pull	1.62	1.8		$I_o = 2mA$ Load = 50pF
	T_R, T_F Push-Pull	Rise, Fall Time Push-pull		18.5	ns	Load = 50pF
	V_{OL} Open Drain	Output Low Voltage Open Drain	0	0.36		$I_o = 2mA$ Load = 64pF $R_{PU} = 1Kohm$
1.8V FS_CR CLKREQ0 (Note 2)	V_{IH}	Input High Voltage	1.26	2.1	V	
	V_{IL}	Input Low Voltage	-0.3	0.54	V	
	$R_{PU/PD}$	Weak Pull-Up or Pull-Down	100	180	Kohm	
	I_{IN}	Input Leakage Current		10	uA	No Pulls
	V_{OH}	Output High Voltage	1.62	1.8	V	$I_o = 2mA$ Load = 20pF
	V_{OL}	Output Low Voltage	0	0.18		$I_o = 2mA$ Load = 20pF
	T_R, T_F	Rise, Fall Time		18.5	ns	Load = 20pF
	C_{IO}	IO Pin Capacitance		2	pF	



I/O Type	Symbol	Parameter	Min	Max	Unit	Notes
1.8V FS_3VT C_P32K (Note 3)	V _{IH}	Input High Voltage	1.26	2.1	V	
	V _{IL}	Input Low Voltage	-0.3	0.54	V	
	R _{PU/PD}	Weak Pull-Up or Pull-Down	150 (typical)		Kohm	
	I _{IN}	Input Leakage Current		10	uA	No Pulls
	V _{OH}	Output High Voltage	1.62	1.8	V	I _O = 1mA Load = 30pF
	V _{OL}	Output Low Voltage	0	0.18		I _O = 1mA Load = 30pF
	T _R , T _F	Rise, Fall Time		20	ns	Load = 30pF
	C _{IO}	IO Pin Capacitance		2	pF	
BRI and RGI 1.8V I/O BRI_DT BRI_RSP RGI_DT RGI_RSP (Note 4)	V _{IH}	Input High Voltage	1.26	TBD	V	
	V _{IL}	Input Low Voltage	TBD	0.54	V	
	R _{PU/PD}					
	I _{IN}					
	V _{OH}	Output High Voltage	1.62	1.8	V	50ohm driver impedance Load = 35pF
	V _{OL}	Output Low Voltage	0	0.18		
	T _R , T _F	Rise, Fall Time	1.5	4.5	ns	
	R _b	Baud rate	4.8	76.8	Mbaud	Tolerance +/- 5%
CNVio (Note 5)	Signal parameters follow the MIPI D-PHY Specifications Rev1.1					

Notes:

1. I2C max speed will be 1MHz (Fast plus Mode). I2C SDA & SCL I/Os must comply with 120ns max rise/fall time. I/O are protected against back-bias up to 1.8V and can withstand I/O voltage when the power supply is off.
2. I/O are protected against back-bias up to 1.98V and can withstand I/O voltage when the power supply is off.
3. Input is 3.6V tolerant. I/O are protected against back-bias up to 3.6V and can withstand I/O voltage when the power supply is off.
4. I/O are protected against back-bias up to 1.98V and can withstand I/O voltage when the power supply is off.
5. The D-PHY I/O pins must comply with the DC electrical specifications in "MIPI Alliance Specification for D-PHY Rev1.1." Specifically, the D-PHY JfP transmitter (JfP to Pulsar) DC characteristics are found in Section 9.1, Table 16. The D-PHY JfP receiver (Pulsar to JfP) DC characteristics are found in Section 9.2, Table 20.



42.4.8 CNVi Power Rails Table

Voltage (V)	Source	Input	Comments
3.3V (M.2 Supply)	Platform VR	3.3V supply pin on Connectivity M.2	Must be always on for CNVi Power gating not allowed
1.8	Platform VR or PCH internal H-LDO PCH pins VCCPHVLDO_1P8[2]	VCCPRIM_1P8[5]	Depends on the presence of a 1.8V platform VR or PCH internal 1.8V LDO. For internal LDO configuration short VCCPHVLDO_1P8[2] to VCCPRIM_1P8[5]
1.05	Platform VR	VCCPRIM_1P05[16] VCCPRIM_CNV_HVLDO_1P05	
1.24	VCCDPHY_1P24[3]	VCCLDOSRAM_IN_1P24[2]	Pins are used for decap only. Connect a 4.7uF cap close to VCCDPHY_1P24 pins and short between VCCLDOSRAM_IN_1P24[2] and VCCDPHY_1P24[3]
3.3 (PCH)	Platform VR	VCCPHVLDO_3P3[1]	For the internal 1.8V configuration only.

42.4.9 CNVi Power-up Sequence

During platform power up the PCH performs a hardware auto-detect handshake to detect the presence of a CRF in the system. From PCH perspective there can be a CRF in the system, or there can be no CRF, in which case Wi-Fi* and Bluetooth are supported by a discrete connectivity module.

The following signals are involved in the CNVi auto detect sequence:

- CRF power supply- 3.3V power pin of the connectivity module (either CRF or discrete)
- RSMRST#- platform global resume reset signal
- CNV_RF_RESET#- GPIO used as a reset for CRF modules (output from PCH)
- CNV_RGI_DT- GPIO used as a strap to detect the CRF present and as a control bus for CNVi (PCH strap and output from PCH)
- MODEM_CLKREQ- GPIO used to activate/deactivate the CRF reference clock (output of PCH)
- 38.4 MHz clock- the CRF reference clock (input to PCH)

The auto-detect is based on the CNV_RGI_DT signal which is initially controlled by the CRF and sampled as a PCH strap during power up.

Inside the CRF chip, the CNV_RGI_DT is actively pulled low (with an approximate strength of 1K ohm to ground). This pull-down is only valid when the CRF power is up and stable therefore it is required that the 3.3V power to the connectivity module will ramp up before any auto-detect sequence starts.

The PCH straps are sampled immediately after the de-assertion of RSMRSET#.

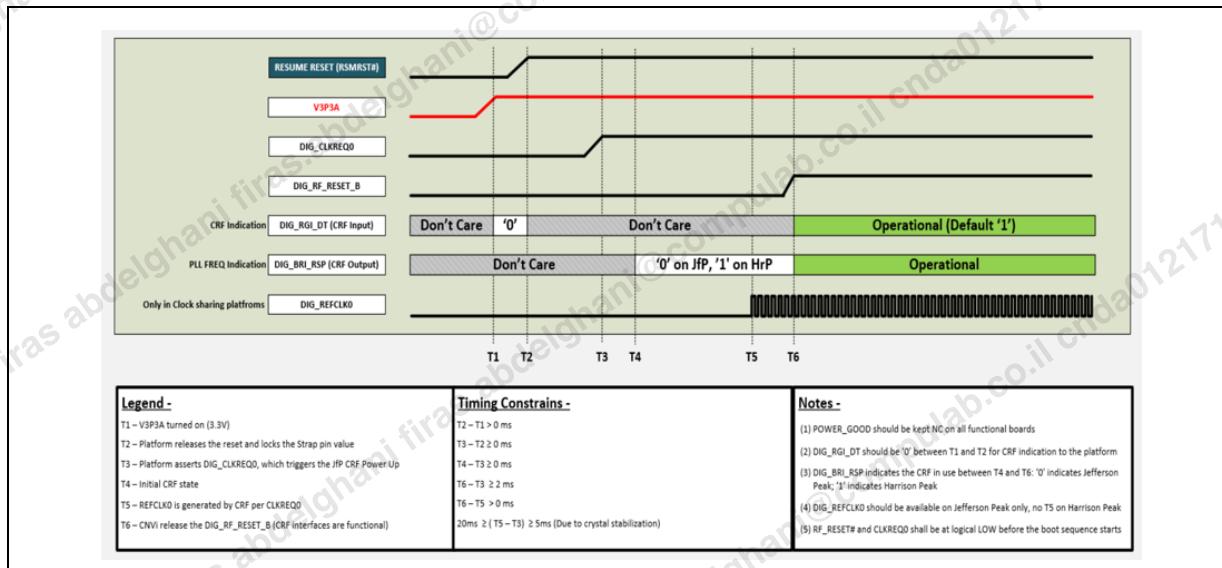
- If the system has a CRF, the value sampled into the strap will be the CNV_RGI_DT pulled to zero. In this case once the straps are sampled they are locked and the PCH HW will be configured for CNVi mode until it is shut down.
- Once CNVi HW is configured in the PCH the CNV_RF_RESET# is de-asserted which causes the CRF to de-activate the 1K pull down of CNV_RGI_DT. The CNV_RGI_DT

GPIO pin defaults to an output of the PCH to become the RGI bus and is set to logical high (which is the CNV_RGI_DT value at rest).

- As part of the CNVi internal boot, the clock request is asserted by the PCH and the CRF clock starts toggling at a frequency of 38.4Mhz. At this point the CNVi initial handshake completes.

During the first point above, if the CRF does not exist, the CNV_RGI_DT value will be driven by on-die or platform pull up resistors (typical 20K). In this case the strap will sample a logical high and the rest of the handshake process will not be performed.

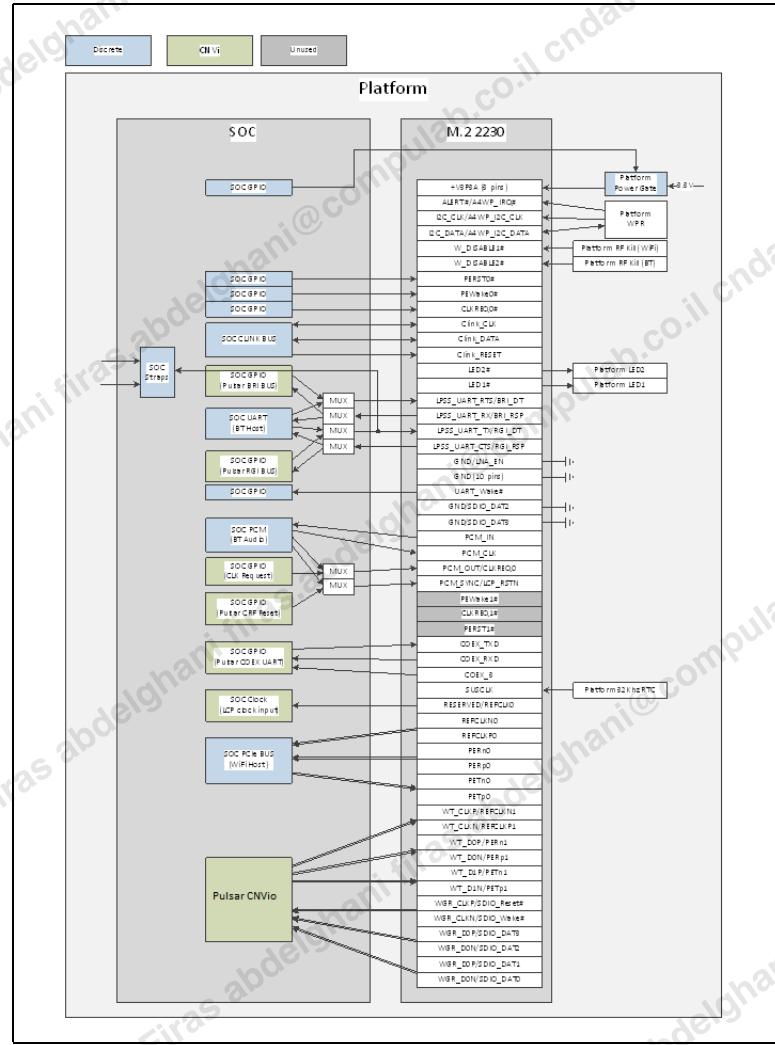
Figure 42-12.CNVi Power up Sequence



42.4.10 CNVi Platform Connections

42.4.10.1 Jumper-less Hybrid Key-E Routing on Motherboard

Figure 42-13.Jumper-less Hybrid Key-E Routing Scheme



42.4.10.2 Connectivity Integration (CNVi) BRI/RGI

The BRI and RGI can operate at Slow speed (4.8Mbps) and at Full Speed (76.8Mbps). Only at power up the bus will operate at 4.8Mbits/sec, and after very short time it switches to full speed. The switching is self-configured by the CNVi hardware.

The BRI and RGI data is over-sampled by a factor of 8 in Slow speed (De-serializer runs at 38.4MHz clock) and by a factor of 8.125 in Full Speed (De-serializer runs at 624MHz clock) in the CNVi CRF module side, and 8.333 in the PCH (Pulsar) side. Both interfaces operate either in Slow or Full Speed at any given time (no mixed mode).



42.4.10.3 Tools for Analysis

BRI and RGI design can be simulated using single-ended trace model to ensure proper signal integrity for the maximum signal bandwidth.

42.4.10.4 Tools for Debug

BRI and RGI can be tested with the CNVio tool or with the EMT tool. This tool will test the design margins and can detect bus errors as well as very marginal signal integrity.

42.4.11 USB 2.0 Port for Bluetooth

The USB port used for Bluetooth is the same whether CNVi or discrete connectivity is used. For CNVi the USB connection is internal to the SoC and there is no USB PHY or external bus required. For discrete connectivity the Bluetooth is connected through the USB pins. In both cases, the same USB port number is used. The USB port number used for Bluetooth in PCH-LP is port 10 and in PCH-H it is port 14.

42.5 CNVio Bus

The CNVio signals connects between the CRF RF companion module and the SoC. They are used as the main data bus for Wi-Fi* to transfer data between the PCH (Pulsar) and the RF companion chip. The CNVio signals electrical characteristics are similar to the DPHY standard. The CNVio protocol used for this bus is proprietary.

CNVio signal specifications are documented in the MIPI-DPHY rev1.1 standard specification (see chapter 7 of the MIPI-DPHY rev1.1 standard revision 1.1: Interconnect and Lane Configuration)

The CNVio bus is source synchronous where each lane has data carried over a differential pair, and each direction may have multiple lanes and a single clock driven by the source.

The CNVio has 2 lanes in each direction, which supports the following bit rates: (per lane)

- 1.28Gbits/sec (with a clock rate of 640Mhz)

42.5.1 Routing Guidelines for CNVio

The CNVio signals connects between the RF companion module and the SoC. They are used as the main data bus for Wi-Fi* to transfer data between the Pulsar and the RF companion chip. The CNVio signals are physically compliant to MIPI-DPHY rev1.1 standard, but have a different (and Intel proprietary) protocol.

We recommend that the design be fully comply with the CNVio routing signal requirements. These requirements are well documented in the CNVio standard specification (see chapter 7 of the MIPI-DPHY rev1.1 standard: Interconnect and Lane Configuration)

The CNVio bus is source synchronous where each lane has data carried over a differential pair, and each direction may have multiple lanes and a single clock driven by the source.

42.5.1.1 Routing

The 2 traces of each lane must be routed as matched as possible. Moreover, since the CNVio uses one clock signal for 2 lanes in each direction, there should also be a good delay matching between the two data lanes and the clock. There are no special delay matching requirements between lanes on opposite directions.

Table 42-8. CNVio Recommended Routing Parameters

Parameter	Value	Comment
Differential pair length matching:	<ul style="list-style-type: none"> Within same layer mismatch: $\pm 10\text{mils}$ (0.254mm) Total length mismatch: $\pm 15\text{mils}$ (0.381mm) 	This parameters may effect EMI and RFI
Characteristic impedance	85 ohm differential	50 Ohm to ground for each trace
Maximum length	10 inch	Notes: The "Maximum Length" considerations for different CNVi solution: <ul style="list-style-type: none"> Connector based M.2 – (M1+M2+M3+M4) Solder down M.2 – (M1+M2+M3)
Maximum resistance	5 ohm	50 ohm to ground for each trace
Shielding	Stripline	Recommended for minimizing EMI/RFI
Delay matching between pairs of the same direction	Better than 80 mil	Including the 2 lanes and the clock in every direction
Vias	Avoid	Recommended to avoid Via connections as much as possible
BER	1E-12	Standard PHY bit error rate for a CNVio lane

42.5.1.2 CNVio M.2 Topology

Figure 42-14.CNVio M.2 Topology Diagram

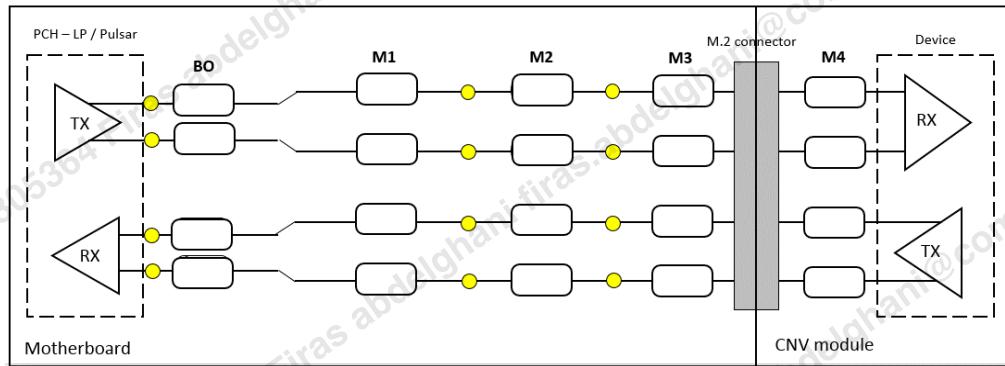
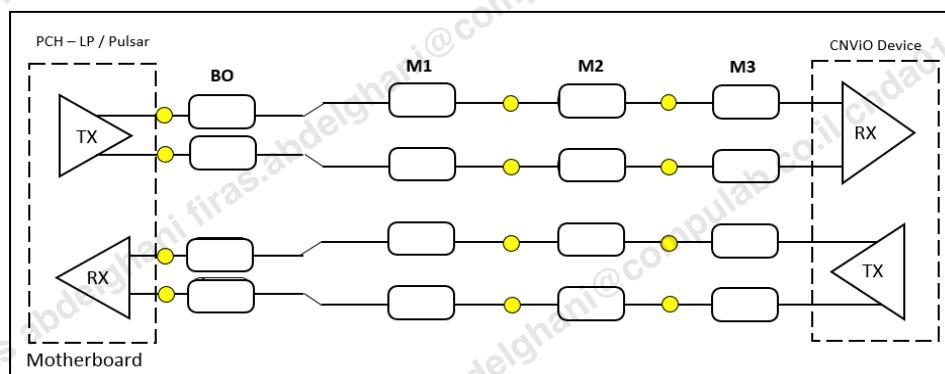


Table 42-9. CNVio M.2 Topology Values

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	3	12.7	254.00	500.00	10000.00
M1	MS/SL/DSL	VSS		213		8385.80	
M2	MS/SL/DSL	VSS		2.5		98.20	
M3	MS	VSS		25.4		1000.00	
M4	MS	VSS					

Notes:

- Number of vias: 2 vias from BO to main Route to device and 1 via underneath the BGA to breakout.
- Reference Plane: Continuous Ground.

Figure 42-15.CNVio Device down Topology Diagram

Table 42-10. CNVio Device Down Topology Values

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	3	12.7	254.00	500.00	10000.00
M1	MS/SL/DSL	VSS		215.9		8500.00	
M2	MS/SL/DSL	VSS		25.4		1000.00	
M3	MS	VSS					

Notes:

- RCOMP Rdc on motherboard is < 0.5ohm.



2. 150 ohm +/-1 % RCOMP on motherboard. The RCOMP signals should be referenced to VSS. Noisy or switching references should be avoided. As board space allows, it is recommended to add a VSS shield at least 4 mils wide placed between RCOMP and adjacent I/O.
3. Continuous GND referencing is preferred for both the topologies. Power plane referencing is also allowed.

Table 42-11. Topology Guidelines

General Guidelines	Value
Number of vias allowed	3
Reference Plane	Continuous Ground Only

Table 42-12. General Guidelines

General Guidelines	Value
Length Matching between P and N within a diff. pair	Within same layer mismatch: \pm 10mils (0.254mm) Total length mismatch: \pm 15mils (0.381mm)
Length matching between Data to CLK lane (board)	< 50 mils (1.27mm)

42.5.2 Tools for Analysis

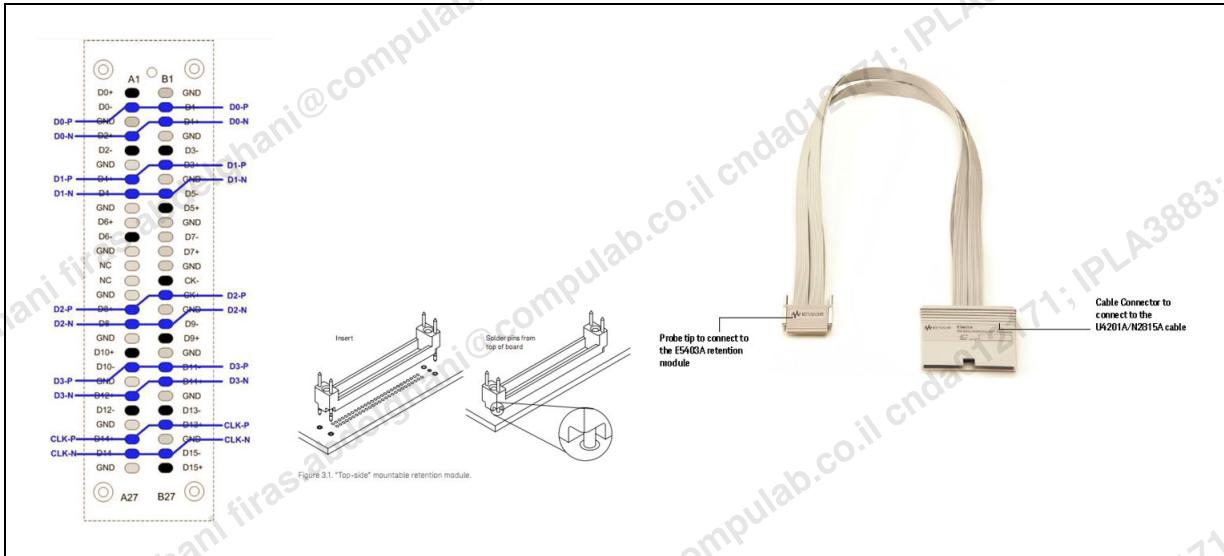
CNVio design can be simulated using differential trace model to ensure proper signal integrity for the maximum signal bandwidth.

42.5.3 Tools for Debug

CNVio can be tested with the CNVio test tool or with the EMT tool. This tool will test the design marginality and can detect bus errors as well as very marginal signal integrity.

42.5.4 CNVio Probing

It is recommended to avoid adding any probing pads or test points to the CNVio traces. However in cases where probing the CNVio bus is needed it is recommended to use a special soft touch probe. A special CNVio analyzer U4421A from Agilent (Keysight) can be used with a special cable and retention module. When designing for using this probing set, the probe footprint is inserted within the CNVio traces while allowing the traces to maintain good impedance characteristics. An illustration of the probe and cable setup is shown in figure below.

Figure 42-16.CNVio Probing Components


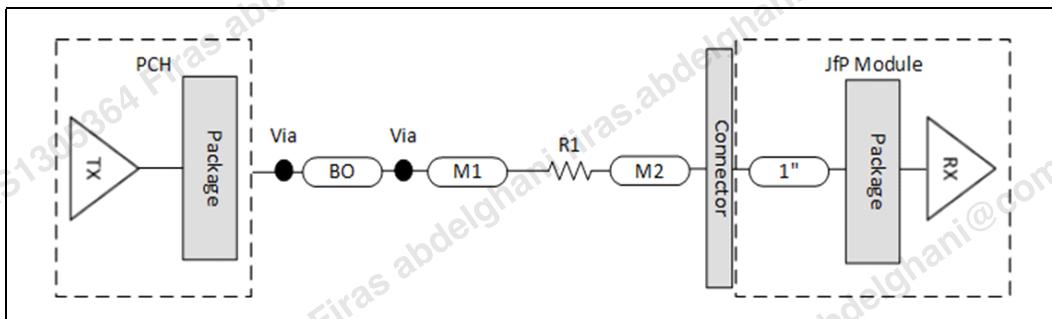
42.5.5 Routing Guidelines for BRI/RGI

These are GPIO signals (1.8V) running between the SoC and the RF companion module. The BRI and RGI signals share the same traces as UART signals (for discrete). Since the UART baud rate is expected to be lower than the BRI/RGI toggle rate it can be assumed the BRI/RGI sets the requirements for this bus.

BRI and RGI are 2 bi-directional busses. These signals have slew-rate controlled I/O's on both ends (SoC and RF companion) which should be optimized to minimize EMI/RFI while maintaining good signal waveform. No special control impedance is needed.

The BRI and RGI packets are ECC protected and with standard routing and signal integrity practices applied, no errors are expected to be noticed on the busses.

42.5.5.1 CNVi BRI & RGI Single Load

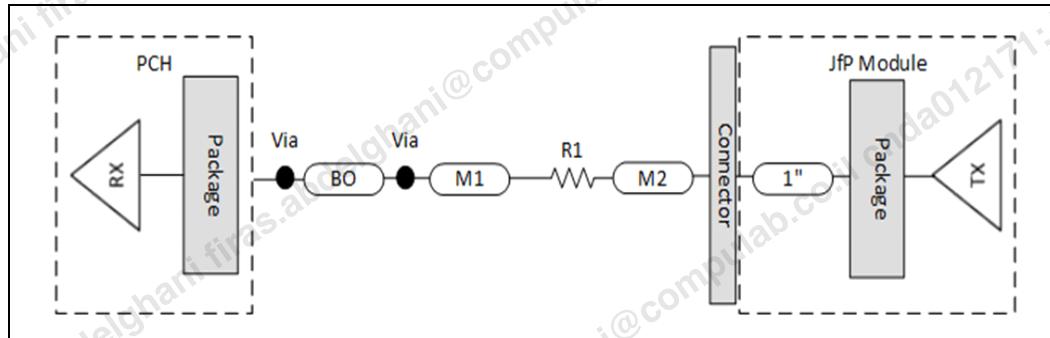
Figure 42-17.CNVi BRI & RGI Single Load (DT) Topology Diagram


**Table 42-13. CNVi BRI & RGI Single Load (DT) Topology Values**

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	N/A	12.7	253.7	500.00	9988.19
M1	MS	VSS	N/A	12.7		500.00	
M2	MS/SL/DSL	VSS	N/A	228.3		8988.19	

Notes:

1. This topology relates to CNV_BRI/RGI_DT signal.
2. Frequency Support: The design guidelines support up to 38.4MHz.
3. Resistor R1 Spec: 33 Ohm, to be placed close to the PCH.
4. Number of vias allowed: 7.

Figure 42-18.CNVi BRI & RGI Single Load (RSP) Topology Diagram**Table 42-14. CNVi BRI & RGI Single Load (RSP) Topology Values**

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils	
				Segment	Total	Segment	Total
BO	MS/SL/DSL	VSS	N/A	12.7	253.7	500.00	9988.19
M1	MS/SL/DSL	VSS	N/A	228.3		8988.19	
M2	MS	VSS	N/A	12.7		500.00	

Notes:

1. This topology relates to CNV_BRI/RGI_RSP signal.
2. Frequency Support: The design guidelines support up to 38.4MHz.
3. Resistor R1 Spec: 22 Ohm, to be placed close to the connector.
4. Number of vias allowed: 7.

Table 42-15. General Guidelines

General Guidelines	Value
Trace spacing between DATA and DATA	5 mils (0.127mm)

General Guidelines	Value
Trace spacing between DATA and other signals	20 mils (0.508mm)

42.5.5.2 Routing Guidelines for RefClk

RefCLK is a 38.4MHz clock signal which is generated by the RF companion module and sent to the SoC. This clock can be used as the SoC main clock (in clock sharing configuration) or as the Pulsar clock (in non-clock sharing configuration). When using the latter option, the SoC should have another clock for its operation, but Pulsar (within the SoC) will always get the 38.4MHz clock coming from the CRF.

The clock signal is 1V nominal, 10Kohm typical resistive load with 35pF load capacitance.

It is recommended to rout the clock with special care while maintaining clock routing practices, preferably as a microstrip to minimize EMI/RFI and susceptibility to noise.

42.5.5.3 Jefferson Peak Crystal Input to CFL Topology Routing Guidelines

Figure 42-19.Jefferson Peak Crystal Input to CFL Topology Diagram

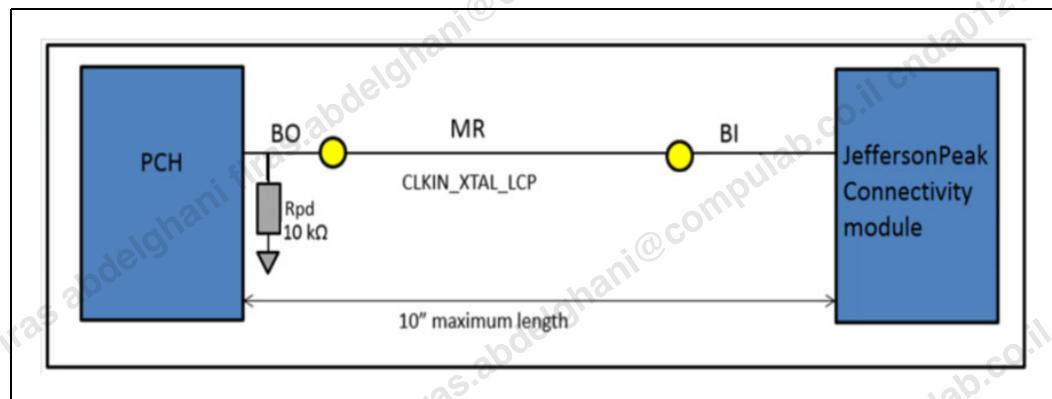


Table 42-16. Jefferson Peak Crystal Input to CFL Topology Values

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mil	
				Segment	Total	Segment	Total
BO or BI	MS/SL/DSL	VSS	1*	12.7	254	500	10000
	MS/SL/DSL	VSS	1*	NA		NA	

**Table 42-17. External Topology Guidelines**

External Topology Guidelines	Value
GND shielding	GND shielding to adjacent signals (especially high speed IO) is recommended
Number of vias allowed	Max 2 vias - recommended to minimize number of vias
Reference plane	Continuous Ground Only; may not reference power planes if routing in stripline or dual stripline, both top and/or bottom reference / adjacent planes MUST be solid continuous ground. Avoid routing directly parallel (under /over) to high current power planes. If unavoidable route signal orthogonal to power plane

42.5.6 Modem Coexistence 3-way UART Connection

In order to allow a "Hybrid Key-E" scheme supporting both connectivity and a cellular modem, there is a need to connect the modem coexistence bus in a configuration that will allow the modem to connect to the connectivity coexistence control logic.

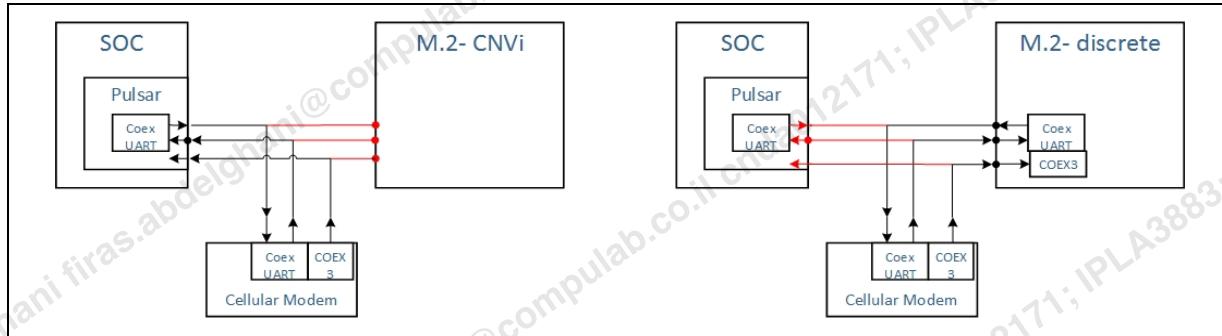
In Intel connectivity modules this logic may reside in the M.2 module or in the SoC, depending on whether CNVi or discrete solutions are used:

- For CNVi, the logic resides in Pulsar
- For discrete M.2 cards, this logic resides in the module

As a result, when a motherboard design contains a modem, and it is desired to be able to support CNVi and discrete on the same M.2 socket, there is a need to have a 3-way connection of the board as shown in figure 17.

One can simplify the routing by adding a jumper resistor to select between the two configurations however this will result in losing the option to swap between CNVi and Discrete on the board. Any such swapping will then require board HW change for changing the jumper resistor position.

Note that when doing this 3-way connection between SoC, M.2 and the Modem there will always be an unused signal which is not optimally terminated for that connection. This signal is shown in red in figure below. The effect of this signal is similar to a stub which adds undesired impedance change to the trace. The effect of this stub on the UART bus depends on several system parameters, distance between the different UART pins, UART bus speed and electrical characteristics of the UART drivers and receivers (referenced to the signal pins). This effect must be considered and analyzed through design practices or simulations to ensure signal integrity is not compromised. For this analysis, the UART baud rate shall be assumed not higher than 4Mbaud.

Figure 42-20.Cox UART for Connectivity/Modem in 3-way Configuration


42.5.7 SoC Termination Requirements

Due to special power up sequencing of the CRF and I/O requirements the SoC I/O shall be terminated according to the following considerations:

The 38.4 MHz clock from CRF to the SoC has an I/O buffer which is not powered when the CRF is initially powered up. The supply to this buffer will only come up following the first clock request from the SoC. To avoid floating input at the SoC clock pin it is recommended to add a weak **pull down** resistor to the SoC pin. The resistor value shall be 10K ohm and it should be located close to the SoC pin. When adding this resistor the design should be checked to ensure it does not distort the clock signal.

The BRI_RSP and RGI_RSP signals from CRF to the SoC have I/O buffers which are not powered when the CRF is initially powered up. The supply to these buffers will only come up following the first clock request from the SoC. To avoid floating input at the I/O pin it is recommended to add a weak **pull up** resistor to the SoC pin with a recommended value of 20K ohm.

The **CNV_RF_RESET#** signal from the SoC to CRF is used as the main reset signal to the CRF during boot. This signal must have a stable value starting from initial power up of the platform and before the CRF power comes up. To ensure that the CNV_RF_RESET# signal is glitch free it is recommended that a **pull down** resistor be connected between the SoC pin and ground. A 75K ohm resistor to ground will ensure the stability of the signal. Since CNV_RF_RESET# is normally held at 1.8V it is expected to consume negligible amount of power (about 43uW continuously).

42.5.8 RF Companion Specifications

The electrical specifications of the JfP chip can be found in the JfP Electrical Spec document (RDC#567240)

42.6 Standard M.2 Connectivity Design Considerations

42.6.1 Standard (Discrete) Connectivity Guidelines

The Coffee Lake platform supports both Integrated (CNVi) and Discrete (Standard M.2) connectivity modules on the M.2 socket. These are the guidelines for using the standard M.2 Wi-Fi*/Bluetooth combo modules.



42.6.1.1 PCIe

- PCIe is the standard M.2 interface for Wi-Fi*.
- PESRT# and PEWAKE# are used for D3 flows it is possible to share these signal with other system components.
 - PEWAKE # signal cannot be shared with other PCIe devices since it is used by a specific device.
 - PERST# signal can be shared. As example Wi-Fi* PERST# can be connected to a platform global PCIe reset signal.
 - Connected standby flows are using RTD3hot. RTD3hot is not using PERST#, and not using PEWAKE#
 - Non-connected standby flows are using D3cold. D3cold is using PERST# and PEWAKE#.
- In S3-5 the platform puts all the devices to D3cold, and will assert PERST# to all of them, as a result PERST# can be shared.
- Wi-Fi* core can still be kept active in D3, but in that case, since it is D3cold, Wi-Fi* will ignore PERST# even if it puts Wi-Fi* into PCIe reset.
- Wi-Fi* core can wake the system using PEWAKE# and there is added value in non-CS platforms to have dedicated PEWAKE# signals, but it is not mandatory.
- To conclude, even in non-connected standby flows the signals can be shared.

42.6.1.2 Connectivity Module Power Control

The platform designer has the following options to control the power rail of the connectivity module:

- **Recommended option (and a must for CNVi support):** Connect directly to a non-switched 3.3V rail. This is the only possible option when the design should also support CNVi.
 - The device will be on as long as the rail provides power.
 - The OEM can save the need to use power switch, but keep connectivity module leakage in the relevant platform states.
- **Optional (not valid for CNVi or dual discrete/CNVi support):** Connect to a 3.3V rail through power switch.
 - Control the switch using SLP_WLAN controlling signal.
 - The SLP_WLAN signal will keep the connectivity awake when needed, and turn it off when not needed.
 - For example, if ME in Sx is not used, and wake on WLAN in Sx is not used, then connectivity can be turned off.

42.6.1.3 Power Feed

It is required to have decoupling caps on the power feeds in each end of the connector.

10uF+0.1uF+0.01uF at one end of socket in support of 3.3 V3V pins 2 and 4.

10uF+0.1uF+0.01uF at the other end of the socket in support of 3.3 V3V pins 70 and 72.

42.6.2 PCIe Host Interface Errata

This section includes several important implementation aspects about PCIe host interface. The platform designer should take these items into account as part of the platform design.

42.6.2.1 Squelch Detect Mechanism

The Squelch (SQ) detect mechanism may not consistently identify PCH wake signaling (TS1 symbols) as valid above SQ Max threshold of 175 mV, as defined in the PCIe spec.

It is important to follow proper platform design and layout guidelines as defined in the PCIe CEM specification to ensure PCH wake signaling (Electrical Idle Detect Threshold - $V_{rx-idle-det-diff-p-p}$ parameter) in the range of:

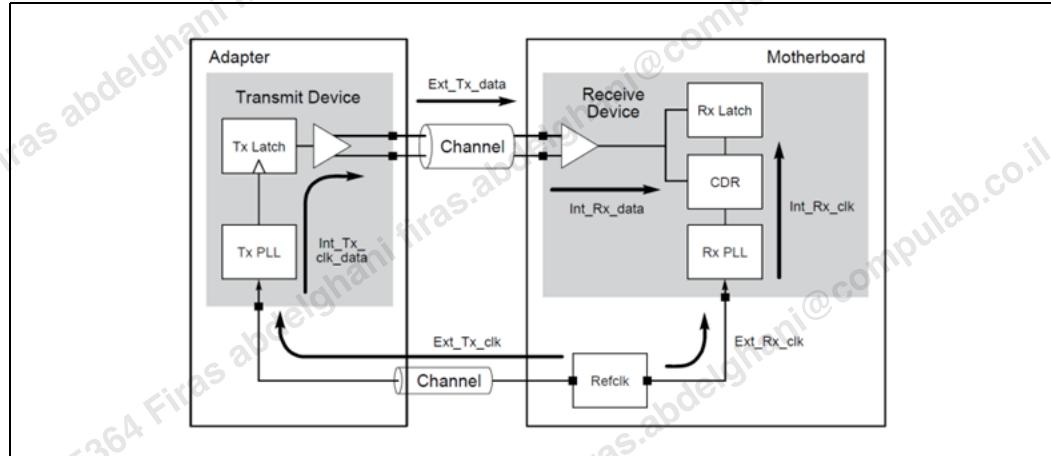
- 65 mV to 280 mV

Customers should design/plan appropriately for all adapters that may be used in a given platform.

42.6.2.2 Common Clock Configuration

PCIe on both platform side (PCH) and WLAN side must operate using common clock configuration. Both PCH and WLAN are configured for this by default (bit 6 is set in registers 0x50 and 0xF0). From hardware perspective, the same reference clock (Refclk) must be used for both PCH and Wi-Fi* card, as shown in Figure below.

Figure 42-21. PCIe Common Clock Configuration



Source: PCI Express Rev 2.0 spec (PCI_Express_Base_Rev_2.0_20Dec06a, figure 4-50)

42.6.2.3 Enabling PCIe Controllers with ASPM

ASPM defines the L states of the PCIe connections, L0, L0s, L1 and L2.

The device supports L1 state, and does not support L0s. This is in order to benefit from the power saving that is achieved with L1 state, while avoiding platform integration complexity which is involved with using L0s state.



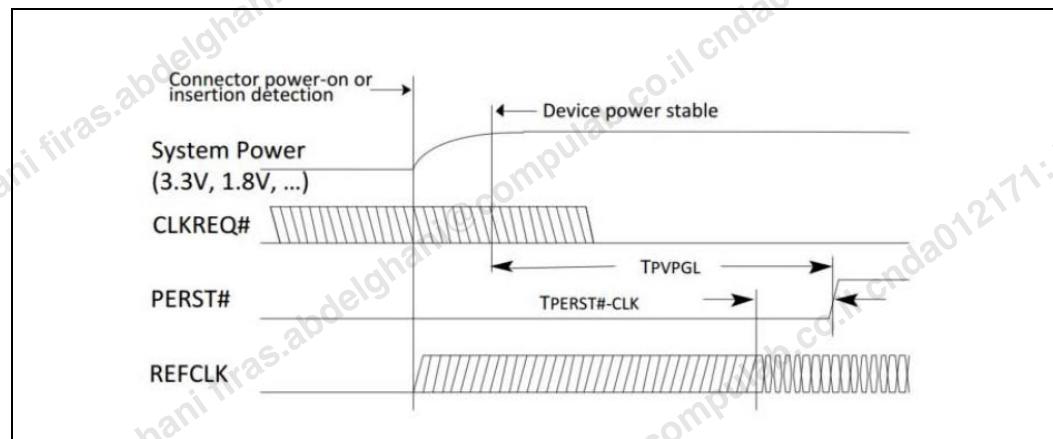
The device supports ASPM optionality ECN, allowing support of L1 without L0s. Therefore, there is no need for special BIOS actions as with previous Intel's wireless products.

42.6.2.4 CLKREQ# Timing

Latest PCIe M.2 Specification does not specify a constraint on when PCIe device should assert CLKREQ# after Power Valid (which is a point where the V3.3 rail reached nominal level).

Refer to the below timing diagram and timing tables taken from PCIe M.2 specification and as can be seen, CLKREQ# assertion timing is not defined.

Figure 42-22. PCIe CLKREQ# Timing



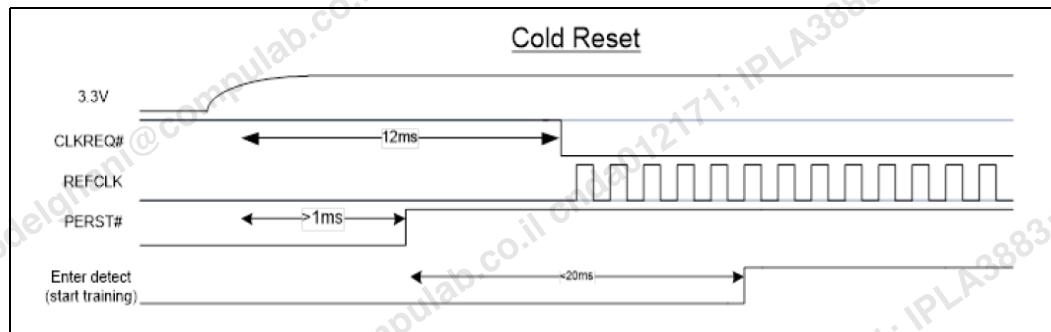
Source: M.2 specification

Table 42-18. Power-up CLKREQ# Timing

Symbol	Parameter	Min	Max	Units
T_{PVPGL}	Power valid to PERST# Input active	Implementation specific		ms
$T_{PERST\#-CLK}$	REFCLK stable before PERST# inactive	100		μ s

Cyclone peak, Thunder Peak and Windstorm peak asserts CLKREQ# within 12ms from Power valid as shown in below figure, these devices complies with the requirement to enter DETECT within 20ms of PERST# de-assertion.

Note: Refer to M.2 device specification to meet the POWER rail to PERST# timing requirements



The PERST# signal rise time needs to meet the limitations listed in below table. This guarantees robust out-of-reset flow of the device and better immunity to noise that can be carried by this signal. In addition, it is required that this signal rise in a monotonic way and avoid a step-like rise.

Table 42-19. Power-up PERST# Timing

Parameter	PERST# Rise Time		
	Intel® Wireless Devices		Snowfield Peak Windstorm Peak Thunder Peak Cyclone Peak
	Stone Peak	Sandy Peak	
PERST# Rise Time	< 20 nSec Monotonic rise		< 150 nSec Monotonic rise
PERST# Ripple/Glitch During Rise Time	< 50 mV glitch during the rise rime phase		< 100 mV glitch during the rise rime phase

§ §



43 Wireless Modules and Antenna Design Guidelines

43.1 Antenna Design Guidelines

A broad range of wireless modules are available suited to different regulatory, performance, and user requirements. This chapter shall discuss the considerations for antenna integration in Coffee Lake processor designs including, but not limited to, antenna performance, placement options, and RF system-level integration.

The Coffee Lake processor may support radios for:

- Wi-Fi (WLAN)
- Bluetooth* (BT)
- GNSS
- WWAN

43.1.1 Antenna Integration

The successful antenna integration on the system is determined through three prime objectives:

1. Ensure good individual antenna efficiency in the frequency bands supported by the respective modem, for all antennas and all modes of operation.
2. Ensure adequate isolation between antennas to:
 - a. Minimize the spatial correlation and mutual coupling between antennas for radios supporting MIMO or diversity, and maximize the benefit that can be derived from the additional transceiver chain.
 - b. Enable the simultaneous operation use-case scenario of multiple radios (co-existence) to be supported without any potential performance degradation. Co-existence of multiple wireless modules and their antennas can become a major problem if not considered in the initial stages of design.
3. Minimize the platform noise coupling into each antenna (in-band noise) which may potentially impact the radio's receiver performance.

43.1.2 Antenna Performance

The individual antenna performance can be characterized by the frequency coverage, efficiency, and peak gain. The isolation between antennas is defined by the S_{21} as measured from the antenna ports on a network analyzer. For radios supporting MIMO or diversity, the MIMO antennas will need to meet the recommended gain imbalance and envelope correlation coefficient limits.

The envelope correlation coefficient can be expressed in the following methods depending on the available figures of merit:



- With the far-field complex antenna radiation patterns, which can be measured in antenna test chambers, the envelope correlation coefficient can be evaluated with the following formula:

$$\rho_e = \frac{\left| \int_0^{2\pi} \int_0^{\pi} (XPR \cdot F_{\theta 1}(\theta, \phi) F_{\theta 2}^*(\theta, \phi) P_\theta(\theta, \phi) + F_{\phi 1}(\theta, \phi) F_{\phi 2}^*(\theta, \phi) P_\phi(\theta, \phi)) \sin(\theta) d\theta d\phi \right|^2}{\left| \int_0^{2\pi} \int_0^{\pi} (XPR \cdot |F_{\theta 1}(\theta, \phi)|^2 P_\theta(\theta, \phi) + |F_{\phi 1}(\theta, \phi)|^2 P_\phi(\theta, \phi)) \sin(\theta) d\theta d\phi \right| \left| \int_0^{2\pi} \int_0^{\pi} (XPR \cdot |F_{\theta 2}(\theta, \phi)|^2 P_\theta(\theta, \phi) + |F_{\phi 2}(\theta, \phi)|^2 P_\phi(\theta, \phi)) \sin(\theta) d\theta d\phi \right|}$$

where ρ_e is the envelope correlation coefficient, F_1 and F_2 are the complex vector field strengths of antenna 1 and 2 respectively, XPR is the cross-polarization ratio, and P is the incident field distribution function.

- In the case where the complex antenna radiation pattern cannot be obtained, an alternative method, which requires the S-parameters and the individual radiation efficiencies, can be utilized to determine the correlation coefficient in the following formula:

$$\rho = \frac{-S_{11}S_{12}^* - S_{21}S_{22}^*}{\sqrt{(1 - |S_{11}|^2 - |S_{21}|^2)(1 - |S_{22}|^2 - |S_{12}|^2)\eta_1\eta_2}}.$$

where ρ is the envelope correlation coefficient, S_{11} , S_{12} , S_{21} , S_{22} are the S-parameters of the two port antenna system measured on a network analyzer, S_{12}^* is the complex conjugate of S_{12} , and η_1 and η_2 are the antenna radiation efficiencies measured with the unused antenna port terminated with a 50 ohm load.

- In the case where only the S-parameters are available, the envelope correlation coefficient can be estimated with the following formula:

$$\rho_e = \frac{|S_{11}^*S_{12} + S_{21}^*S_{22}|^2}{(1 - |S_{11}|^2 - |S_{21}|^2)(1 - |S_{22}|^2 - |S_{12}|^2)}$$

The envelope correlation coefficient calculation methods shown above are described in the following papers:

- Ying et al.; "Characterization of multi-channel antenna performance for mobile terminal by using near field and far field parameters," COST 273 TD(04)(095), Goteborg, Sweden, 2004.*
- Hallbjorner, P.; "The significance of radiation efficiencies when using S-parameters to calculate the received signal correlation from two antennas," Antennas and Wireless Propagation Letters, IEEE, vol.4, no., pp. 97- 99, 2005*

The following tables summarize the antenna performance recommendations for each wireless system, the isolation recommendations, and the recommendations for different modes of operation.

**Table 43-1. Antenna Performance Recommendations**

Antenna	Frequency GHz	Type	Max Size of Antenna Element mm	Efficiency ¹ dB	Peak Gain dBi	MIMO Metrics
WLAN	2.40-2.49 5.15-5.85	PIFA/ Slot	35x8x1	-3.9 (2.4G) -4.4 (5G)	<2 (2.4G) <3.5 (5G)	Correlation Coefficient < 0.3, Gain imbalance < 1 dB
Bluetooth*	2.40-2.49	PIFA/ Chip	35x8x1	-3.9	<3	N/A
GNSS ²	1.56-1.61	PIFA	15x5x2	-3.5	<2	N/A
WWAN M.2 HSPA (2G, 3G)	0.82-0.96 1.71-2.17	PIFA	75x13x2	-4 (f<1GHz) -3 (f>1GHz)	<2	Correlation Coefficient: -> ecc < 0.5 (f < 1GHz) -> ecc < 0.4 (f > 1GHz) Gain imbalance < 1 dB
WWAN M.2 LTE (2G, 3G, LTE)	0.70-0.96 1.42-1.51 1.71-2.17 2.30-2.36 2.50-2.70 GNSS ²	PIFA	75x13x2	-3.5 (f<1.6GHz) -3 (f>1.6GHz)	<2	Correlation Coefficient: -> ecc < 0.5 (f < 1.6GHz) -> ecc < 0.4 (f > 1.6GHz) Gain imbalance < 1 dB

¹ Cable length is assumed to be 600 mm (1.13 mm OD coax) for the antenna efficiency targets. Actual cable length will vary based upon the chassis.

² GNSS (i.e. GPS, GLONASS) antenna is usually expected to be shared with WWAN Aux antenna. It is also possible that GNSS antenna for non WWAN SKUs is either discrete or shared with WLAN antenna. In either case, the efficiency numbers listed above are recommended.

Table 43-2. Isolation Recommendations

Antenna Ports	Wi-Fi	Bluetooth*	GNSS	WWAN/LTE
Wi-Fi	25 dB nominal	25 dB nominal ¹ (15 dB min)	25 dB	25 dB ² (15 dB LTE Band7 ³)
Bluetooth*	25 dB nominal ¹ (15 dB min)	N/A	25 dB	25 dB (20 dB LTE Band7 ³)
GNSS	25 dB	25 dB	N/A	shared
WWAN/LTE	25 dB (15 dB LTE Band7)	25 dB (20 dB LTE Band7 ³)	(shared)	25 dB

¹ BT-Wi-Fi isolation translates to Wi-Fi main to Wi-Fi Aux isolation for the case where BT antenna is shared with Wi-Fi. For best performance, recommended isolation > 35 dB. Nominal performance with limited degradation can be seen with isolation > 25dB. Co-existence solution allows functionality down to 15 dB isolation with reduced performance.

²Without LTE band 7 and without a co-existence mechanism between Wi-Fi and WWAN modules, 30 dB isolation is the best, but 25 dB is acceptable as indicated shown above

³Without a coexistence scheme between WLAN and WWAN, additional filtering at both WWAN and WLAN modules is required to operate at 15 dB isolation. Careful consideration of the total system solution is required for this case

Table 43-3. Recommendations for Different Modes of Operation

Description of Lid Mode	Clamshell (Open Lid)	Tablet	Closed Lid
Antenna performance recommendations	As in Table 43-1	As in Table 43-1	3 dB lower than values in Table 43-1



43.1.3 Antenna Placement

The following must be considered when deciding the placement of antennas:

- **Modes of Operation:** For devices which enable different modes of operation (i.e. Clamshell, Tablet, and Closed Lid), careful consideration of the environment around the antenna in each configuration while deciding the antenna placement is necessary to deliver the desired user experience in all modes of operation.
- **Keep-Out-Zone (KOZ):** A metal-free KOZ is typically required to integrate the antenna in traditional designs. The physical size of the antenna will depend on the target frequencies, bandwidth, and performance requirements of the antenna. Antennas with larger geometric footprints tend to provide better performance. The non-metallic materials (i.e. plastics) also need to be assessed since different materials properties may have different effects to the antenna characteristics.
- **Lossy Structures:** Separation of the antenna radiation elements from lossy structures, such as the LCD enclosure, will provide better bandwidth. The separation required for WWAN is higher than that required for Wi-Fi. In general, lower operational frequencies require larger separation compared to higher operational frequencies. Also, larger bandwidth considerations require larger separation from nearby metallic structures. For WiGig, this separation is crucial and more details can be obtained from Section 9.5 WIGIG Product Guidelines.
- **Grounding:** Unbalanced antennas require a ground reference, which is typically the chassis or the back of the display. The size of the ground reference needs to be considered as part of the antenna design.
- **Cable Routing:** Each antenna will require a coaxial cable to connect to the radio module's RF port. Cable routing that avoids regions with noise and minimizes cable lengths is recommended to minimize the platform noise impact and cable loss. In the case where the module is in the base and the antenna is in the display, the coaxial cable will need to be fed through the hinges. The size of the mechanical hinge places a restriction on the number of cables that can be fed through and the diameter of the cables. Typical RF coax cables can range in outer diameter (OD) from 0.81 mm to 1.37 mm; however, the RF connector receptacle defined by the M.2 module specification will only accept mated plugs with either 0.81 mm OD cables or 1.13 mm OD cables. Refer the respective radio module's product description for the RF connector type.
- **Cable Loss:** Coaxial cables will introduce an insertion loss depending on the diameter, length, and frequency of interest. Thicker coaxial cables tends to be less lossy while being more expensive compared to thinner cables. Lower loss cables are also available from vendors which will reduce the total cable loss especially for long cables. Double shielded cables are useful in ensuring that radio module sensitivity degradation is limited due to the cable picking up platform noise when routed through the platform.
- **RF Exposure (SAR):** Regulatory bodies, such as FCC and CE, define detailed requirements for the allowable RF exposure for devices which generate RF electromagnetic fields. Specific Absorption Rate (SAR) is a measure of the rate in which energy is absorbed in body tissue due to EM energy from an antenna. and is a prime consideration for placement of antennas, especially for higher power radios such as WWAN. For WiGig, the Maximum Permissible Exposure (MPE) is used to determine the RF exposure limit of the radio implementation. In general, the antennas should be located in areas which will not be in close proximity to the human body in any mode of operation. Refer to the published guidance from FCC for more details on the RF exposure requirements.



- **Isolation between antenna ports:** To improve the isolation between antennas, the following methods can be employed which include, but is not limited to:
 - i. Spatial diversity - larger spatial separation between antennas is one way of increasing the isolation between ports of radio modules that operate in bands that are close to one another.
 - ii. Polarization diversity - in some instances where the antennas have polarization discrimination, the relative orientation of the antennas can be used to improve isolation and enhance performance.
- **Platform Noise:** Various components in the system, such as display/touch circuits, memory, PLLs, cameras, clocks, USB/HDMI ports, and other high speed IO, may generate noise which can couple to the antennas and/or coax cables and thus degrade the wireless radio's receiver performance. Careful consideration needs to be employed with respect to antenna placement and cable routing to avoid these noise sources and minimize the platform noise impact to the receivers. With detachable tablets and convertible notebooks, the proximity of the antenna to the base components needs to be especially considered during the initial floor planning.
 - Internal studies have found that 3D cameras, which utilize the USB3 interface to communicate with the motherboard, is a source of broadband RF noise which may impact the antennas in the vicinity. The camera noise may impact the radio's receiver performance through the antenna in two ways:
 - i. Conducted noise which flows from the camera through the shared ground plane (chassis) and in to the antenna through the antenna ground connection. To reduce the noise coupled in to antenna, the ground plane should be manipulated to re-direct the current flow from the camera away from the antenna.
 - ii. Radiated noise from the 3D camera interface (especially the USB3 connector), may couple to the antenna and hence desensitize the radio receiver. In general, the antennas should be separated from the 3D camera and USB3 bus to avoid any degradation to the radio's receiver performance. Studies have shown that the antenna should be at least 15 mm away from the USB3 connector for minimal impact to WWAN and Wi-Fi radios. Shielding of the camera and USB3 connector is also recommended.

43.1.3.1 Antenna Placement Options for Multi-Mode Devices

Two potential antenna placement options are shown in the figures below for clamshells or multi-mode devices such convertibles and detachable Ultrabook™. The target form factor is a 14.1 inch (3581.4 mm) notebook, but it is not limited to this size. Additional consideration will need to be applied to the RF clearance in the base around the antennas for multi-mode devices when in Tablet or Lid-Closed modes.

The module selection includes support for 2x2 MIMO Wi-Fi/BT, and 1x2 WWAN. GNSS is assumed to be combined with WWAN Aux antenna (AGPS/GPS).

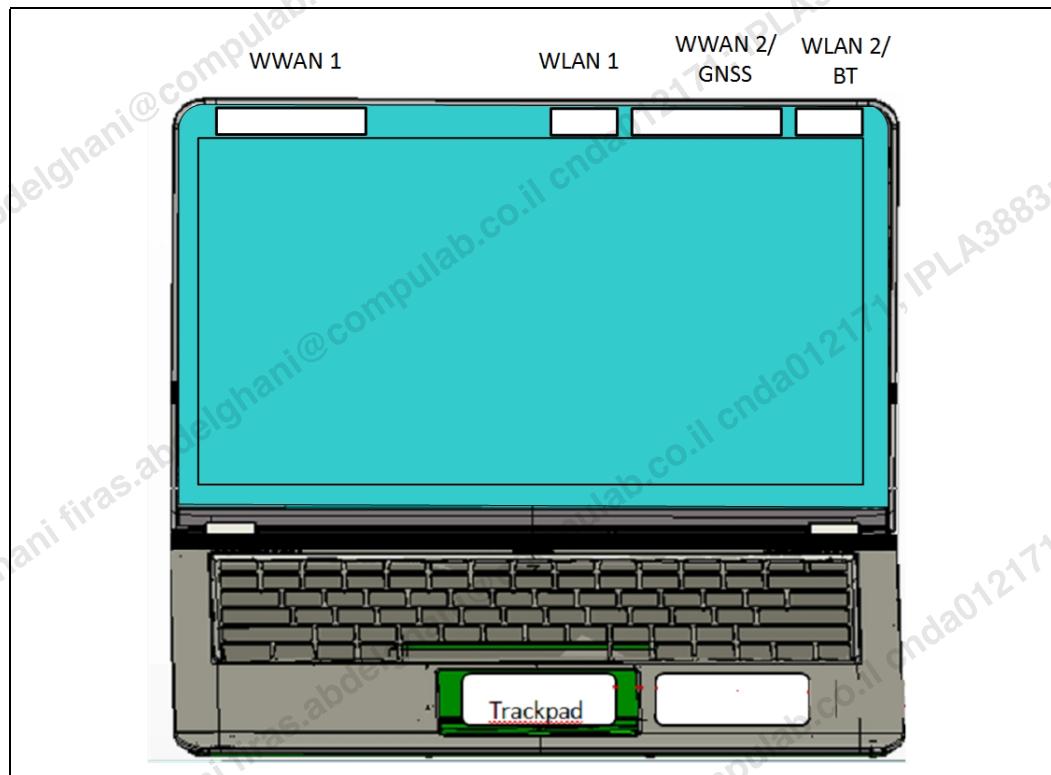
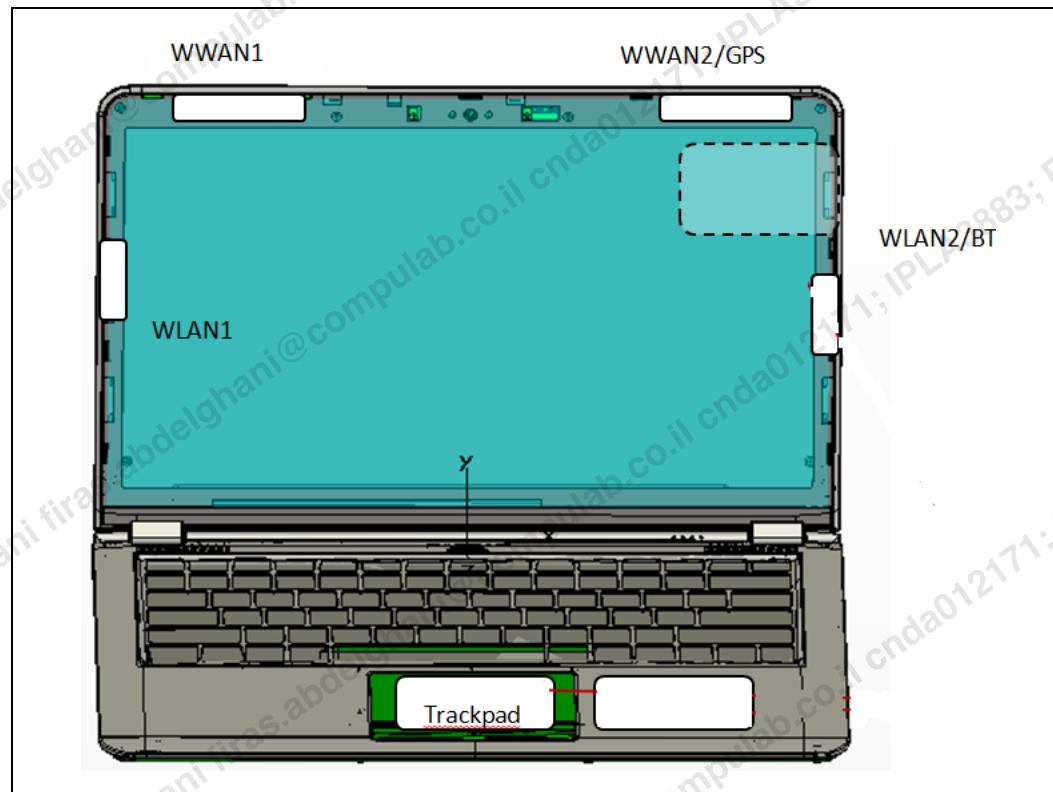
Figure 43-1. Antenna Placement Option 1

Figure 43-2. Antenna Placement Option 2

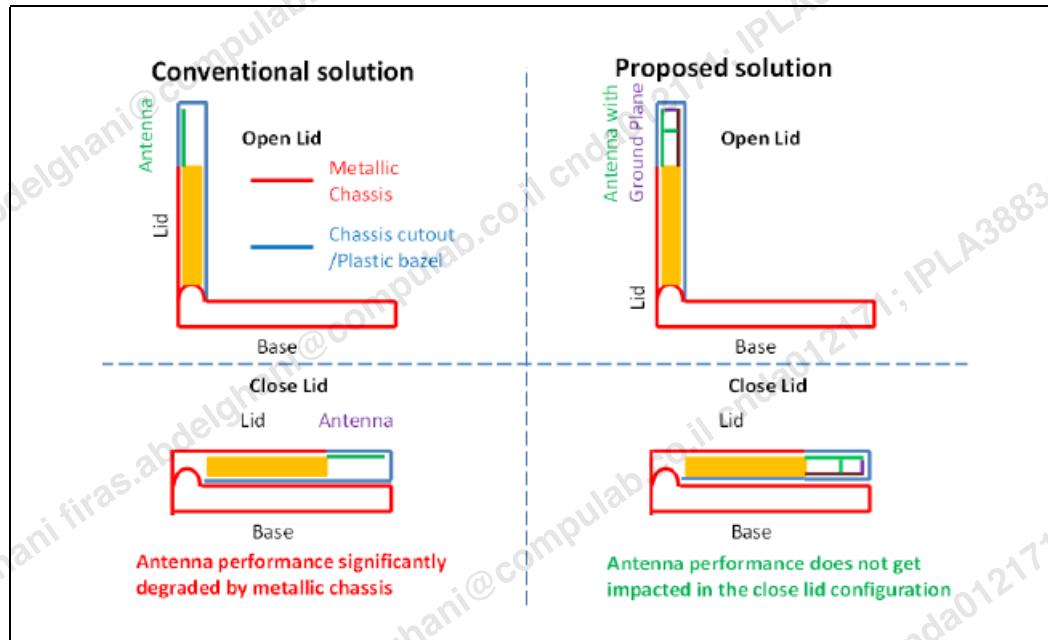
43.1.3.2

Antenna Placement in Metallic Chassis

Many platforms with the U-processor design utilize metal materials for the surface covers, commonly referred to as metallic chassis. The antenna must be placed such that there is sufficient clearance from metal to enable good wireless performance. When there are metal surfaces surrounding the antenna, it is recommended to have plastic sections or insert molded plastic in the metal covers to provide an RF transparent window which will not degrade the antenna performance and thus enable good wireless connectivity in all modes of operation. Other potential options include integrating the antenna on the base (keyboard side) of the platform or utilizing the hinge area. Care should be taken to ensure potential EMI from adjacent I/O connectors do not interfere with the antenna reception.

The following placement options may be considered for Closed Lid mode:

1. **Non-Metallic Chassis/ Metal Chassis with cutouts:** A non-metallic chassis will not cause issues in Closed Lid mode. In the case of a metallic chassis, cutouts may be employed to provide required clearance for the antenna on the A and B-covers. When the lid is closed, the antenna must not rest closer than 5 mm to the EMI coating (or metal) on the C-surface. A suitable plastic cutout, with a recessed EMI shield maybe required to achieve both ESD and EMI protection and good closed lid performance.
2. **Metallic chassis with no cutout on C-surface:** A dielectric loaded antenna maybe placed for Wi-Fi operation on the B-surface, with a cutout on the A-surface. Such a dielectric loaded antenna can operate with a metallic B-surface, which also shields the antenna from the changes introduced by closing the lid. The figure below depicts this solution.

Figure 43-3. Potential Solution for Metallic Chassis with Lid-Closed Operation


- Due to the Tent Mode test configuration for convertible notebooks defined by Intel Regulatory, or in the case of a detachable tablet, the antenna on the A-cover is the worst-case for the body SAR requirement in touch condition and will result in significant transmit power reduction for WWAN and possibly even Wi-Fi. (Same applies for detachable tablet notebooks)

3. **Base mounted Wi-Fi antennas:** Antennas can be placed in the hinge area on the base of a metallic chassis notebook, with a plastic cutout near the hinge. The hinge must be such that when the lid closes, the area in the base where the antennas are housed is not shielded completely by the lid. Special consideration must be given to maximizing the separation between the antenna and the human body below the D-surface to pass SAR requirements with low-risk. Platform noise pickup from base mounted antennas needs to be measured before committing to a particular location as there is a higher risk of impact from platform noise due to the closer proximity of the antennas to the motherboard.
4. **Slot antennas cut into the chassis:** Slots can be cut into the A-surface of the antenna, near the apex of the lid and the cutout can be covered with plastic inserts. Such an antenna would be integrated into the chassis and special care must be given to the feeding mechanism, especially when materials not amenable to soldering such as aluminum are used. Multiple antenna SKUs and/or revisions will imply multiple chassis SKUs and/or revisions, so this option will need to be considered very early in the design cycle.

43.1.4 RF System-Level Integration Recommendations

43.1.4.1 Wi-Fi

Platforms typically support 2x2 (and some 3x3) MIMO configurations for Wi-Fi. In addition to meeting the efficiency requirements set forth in [Table 43-1](#), some additional system level recommendations are listed in [Table 43-4](#) below.

**Table 43-4. Additional Recommendations for Wi-Fi MIMO Operation**

1	Difference in Noise coupling into Main and Aux antennas	< 1 dB
2	Absolute value of noise coupling into Main and Aux antennas	< 3dB de-sense from noise floor

In addition the antenna specs, the following considerations are brought to attention:

- Modern Standby Support (previously Connected Standby or InstantGo)
 - The platform may need to maintain the Wi-Fi connection while in standby and in any mode of operation such as clamshell, tablet, closed lid, detached, and/or convertible modes. SAR requirements will need to be met and active states must be achievable in each of the above operation modes.
- Specific Absorption Rate (SAR)
 - In situations where the platform cannot meet regulatory RF exposure requirements, the radio module's RF transmit power may need to be reduced.
- In-Device Co-Existence Interface
 - Refer to the WWAN section below for more details on the IDC interface.

43.1.4.2 Bluetooth*

A majority of platforms are expected to use the combo Wi-Fi–BT modules. The combo modules implement co-existence schemes which allow for simultaneous operation of Wi-Fi and Bluetooth* with isolation down to 15 dB; however, higher isolation offers better performance and robustness and is recommended as shown in [Table 43-2](#).

If a discrete Bluetooth* module is implemented, the isolation between the BT antenna and each Wi-Fi antenna will need to meet the isolation recommendations in [Table 43-2](#). In platforms where Wi-Fi Aux antenna is also shared as the BT antenna, the Wi-Fi to BT isolation becomes the same as Wi-Fi Main to Wi-Fi Aux isolation.

43.1.4.3 GNSS

Global Navigation Satellite System (GNSS) includes GPS, GLONASS, Galileo, Beidou, and other regional systems. Two potential integration options (and corresponding antenna choices) are supported for GNSS:

1. GNSS on the WWAN module. The WWAN Aux antenna will be required to support GPS and GLONASS frequency bands as defined in [Table 43-1](#). The module will filter the GNSS signal to the GNSS modem integrated in the module.
2. Discrete GNSS solution: A standalone GNSS antenna is required, which will be connected to the RF front end of the discrete GNSS modem implementation.

43.1.4.4 WWAN

Antenna efficiency requirements for WWAN (HSPA or LTE) antennas are listed in [Table 43-1](#). WWAN modules support two antennas (Main and Aux). The WWAN-Main antenna is capable of transmit and receive functions. The WWAN-Aux antenna is a receive-only antenna and is expected to also support the GNSS frequencies.

In addition the antenna specs, the following considerations are brought to attention:

- Modern Standby Support (previously Connected Standby or InstantGo)
 - The platform may need to maintain the WWAN connection while in standby and in any mode of operation such as clamshell, tablet, closed lid, detached, and/or convertible modes.



convertible modes. SAR requirements will need to be met and active states must be achievable in each of the above operation modes.

- Specific Absorption Rate (SAR)
 - In situations where the platform cannot meet regulatory RF exposure requirements, the radio module's RF transmit power may need to be reduced. The WWAN modem has the capability of implementing dynamic power reduction (DPR) with the co-integration of a SAR proximity sensor. SAR proximity sensor pads will need to be implemented around the WWAN transmit antennas (WWAN-Main) and trigger the SAR sensor controller upon detection of the human body to send a signal through GPIO on PCH via SW or directly to the module's DPR pin. Upon receiving the trigger signal, the module will be responsible for reducing the radio's transmit power to levels required to pass the SAR limit.
 - Refer to FCC's documentation for details on RF exposure requirements.
- Tuner and Tunable Antennas:
 - It is recommended that there should be provisions to support antenna tuners with specific antenna and tuner type provided by Intel. Several antenna vendors are offering both tunable and non-tunable (passive) WWAN antennas. The passive antennas are typically easier to integrate but are larger (75 mm x 13 mm x 2 mm for global coverage LTE). The tunable antennas can be potentially smaller in size but require traces from the motherboard/module to be routed to the antenna tuning circuitry, as well as modem support to implement and verify the active tuning intelligence.
 - The Intel WWAN module can control a tuner module by means of 4 GPIO lines from the M.2 module as shown in [Table 43-5](#). Board space for the tuner and additional tuning components and routing space for the power and control signals will need to be taken into account.

Table 43-5. Intel WWAN Antenna Tuning GPIO Description

Signal Name	SMARTi Signal	M.2 Connector Pin	Direction (WWAN)
ANTCTL0	GPO8	59	O
ANTCTL1	REFE_SDATA/GPO13	61	IO
ANTCTL2	REFE_SCLK/GPO14	63	O
ANTCTL3	REFE_VIO/GPO12	65	O

- Selection of tuning components is implementation specific and the recommended values are not hard requirements. See table [Table 43-6](#) and [Table 43-7](#) below for M.2 module specifications and recommendations with respect to tuners. Please contact Intel RF support team for additional options.

Table 43-6. M.2 Module Specifications

Parameter	Value	Comments
Voltage	1.8 V	Applied to both GPO and REFE
max source/sink current	-/+ 5 mA	For GPO operation. At max current up to 0.5 V output voltage drop can occur
REFE_VIO	20 mA	Shared between up to 8 slaves at 1.25 mA per slave plus capacitive load
REFE version	1.1	
Maximum REFE frequency	26 MHz	13 MHz optional
Number of supported tuners	configurable	Please contact Intel RF support team for details

**Table 43-7. M.2 Module Recommended values for Tuners**

Parameter	Value	Comments
Switching Time	<50 uS	Switching between states - REFE or GPO controlled switches
Tuner boot time	<50 uS	Time between VIO goes high and tuner is ready
REFE bus length	REFE 1.1	According to MIPI specification and depending on capacitive load

- In-Device Co-Existence Interface
 - It is recommended that platform designs implement two key mechanisms to improve coexistence when integrating Intel Connectivity and WWAN modules with the potential for simultaneous operation.
 - i. Maximize the isolation between Wi-Fi and WWAN antennas beyond 15 dB which will ease simultaneous operation (see [Table 43-2](#)).
 - ii. Implement the In-Device Coexistence interface connection on the system between the Connectivity and WWAN modules to enable the use of the smart co-existence solution. [Table 43-8](#) is an example of how the 3 coexistence signals for the IDC interface should be connected when the Intel Connectivity and WWAN solutions are implemented as modules plugged into M.2 compatible sockets on the platform.

Table 43-8. In-Device Coexistence Interface

Intel Coexistence Signal description (Signal Name)	Pin# in Connectivity socket	Signal Direction	Pin# in WWAN socket
IDC_UART_TXD (COEX1)	48	←	64
IDC_UART_RXD (COEX2)	46	→	62
GNSS_EXT_FTA (COEX3)	44	←	60

§ §



44 Platform Telecom Design Guidelines

44.1 Safety Rules

Ensure safety compatibility by meeting regulatory requirements. The two standards that are commonly used to evaluate Safety are:

- United States Federal Communication Commission/ Canada UL/CSA 60950-1 Edition (2003)
- European Union, and Mutually Recognizing Countries, International Electro technical Commission's IEC 60950-1 - 1st Edition (2001-10) (with CB certificate) or EN 60950-1: 2001 (with CB certificate) (or 60950-1: 2006) (2006 version required after 1/12/2010)

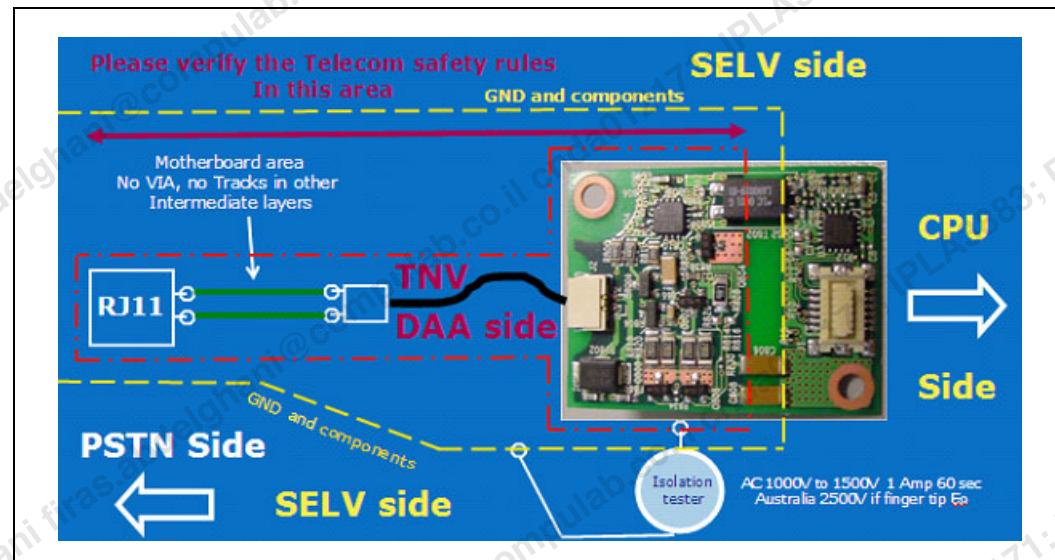
44.2 EMC Rules and Regulations

Ensure Electromagnetic Compatibility (EMC) by meeting regulatory requirements. The two standards that are commonly used to evaluate emissions are:

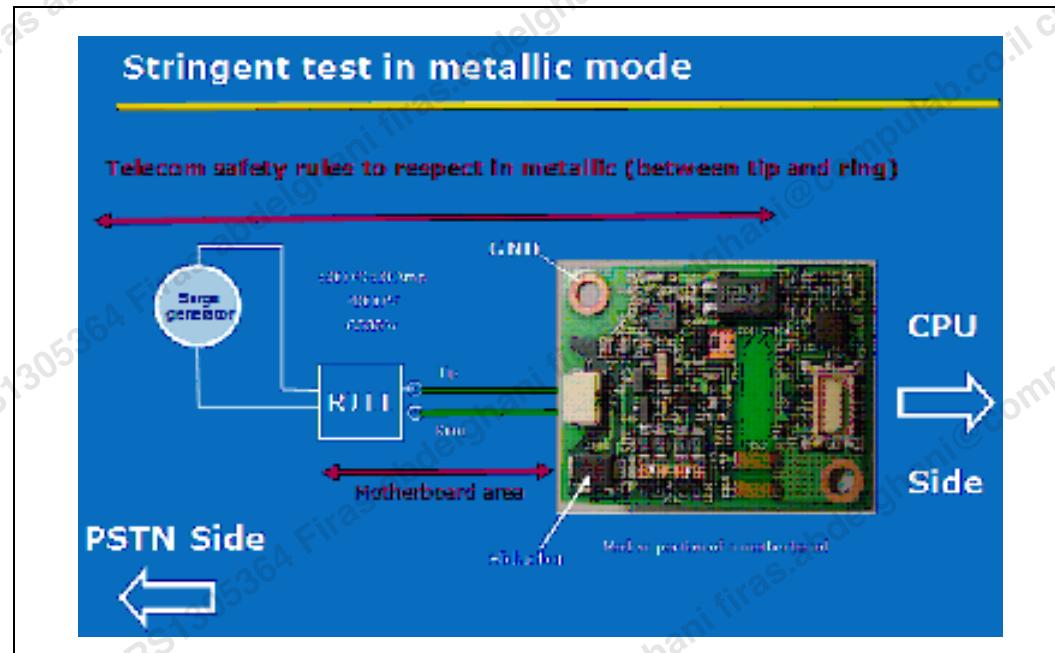
- United States Federal Communication Commission (FCC) Title 47 CFR, Part 15, Subpart B §15.107, §15.109.
- European Union, and Mutually Recognizing Countries, International Electro technical Commission's International Special Committee on Radio Interference (CISPR) Publication 22 class B limits also known as CISPR22 or EN 55022. The seven standards that are commonly used to evaluate immunity for the European Union and Mutually Recognizing Countries IEC 61000-n-n are described in Chapter 49, "Electromagnetic Compatibility".

44.3 Telecom Safety Considerations

To pass the FCC (Federal Communication Commission) and other regulating agency's Telecom standards, digital system designers have to consider the specific Telecom safety isolation between the TNV (DAA side) and the SELV areas. This isolation is measured under 1000 Volts 1 Amp during 1 minute in USA FCC, 1500 Volts 1 Amp during 1 minute in Europe and 2500 Volts 1 Amp during 1 minute in Australia for specific finger tip detection design.

**Figure 44-1. Telecom Safety Considerations-Generic Block Diagram and Isolation**

To pass the FCC (Federal Communication Commission) and other regulating agency's Telecom standards, digital system designers have to consider the specific Telecom surge test between Tip, ring and Ground (metallic between Tip and Ring and longitudinal between Tip/Ring tied together and Ground). The surge tests are applied up to 1500 Volts for USA FCC, 4000 Volts for International K21 and up to 6000 Volts for some OEM recommendations. The modem/circuit traces must survive after these surges.

Figure 44-2. Telecom Safety Considerations-Stringent Test in Metallic Mode

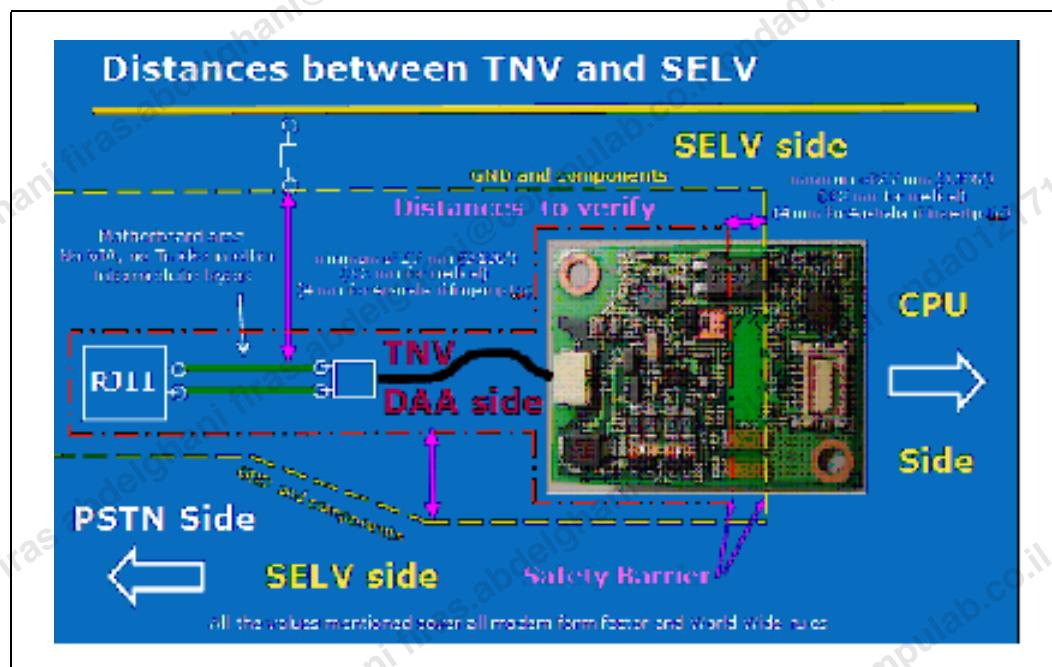
44.4 Configuration

The following sections discuss PCB design techniques which must be applied to fulfill the isolation and surge test limits.

44.4.1 Isolation

A minimum distance of 106.3 mils (2.7 mm) must be respected between all components of the TNV/DAA area and the SELV area (126 mils (3.2 mm) for the medical equipment and 157.48 mils (4 mm) for Australia for specific finger tip detection design).

Figure 44-3. Board Level Design Considerations-Isolation



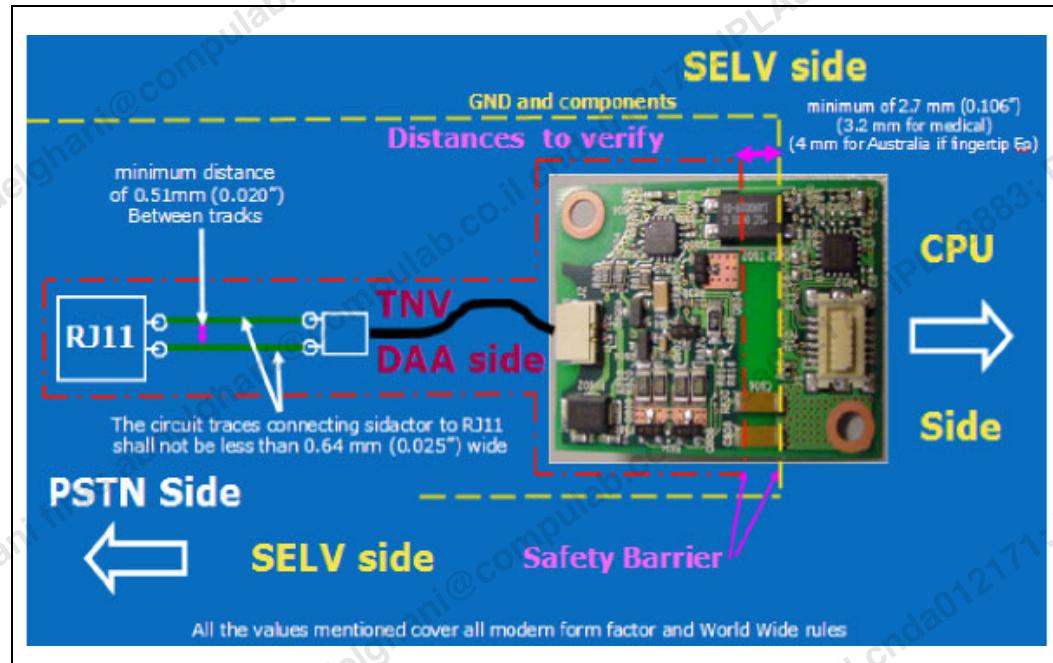
44.4.2 Surge

In the TNV/DAA area a minimum distance of 20.08 mils (0.51 mm) must be respected between the Tip and Ring tracks, the circuit traces connecting the sidactor to the RJ11 shall not be less than 25.2 mil (0.64-mm) wide, no VIA and no tracks in the other intermediate layers can be installed in this area.

For the following figure, keep in mind that Intel is no longer developing such devices. The use of the following configuration is at the risk of designer (mainly at the OEM level).

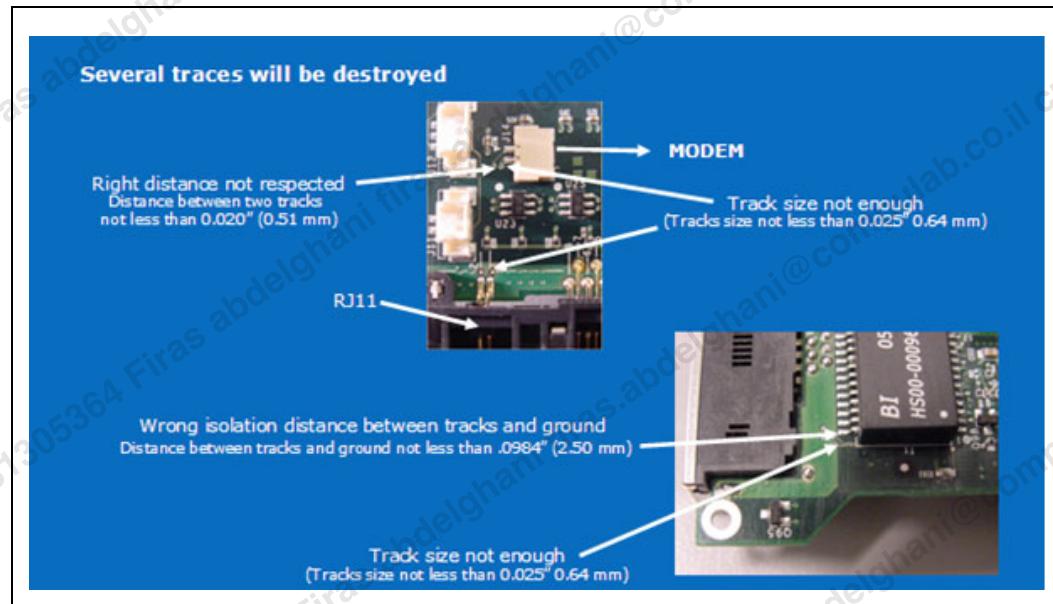


Figure 44-4. Board Level Design Considerations-Surge (Distances inside TNV)



44.4.3 Example of Wrong Implementation

Figure 44-5. Board Level Design Considerations-Example of Wrong Implementation





44.5 Additional Guidelines

Table 44-1. Component Placement Review Checklist

Item NO.	Description	Y/N
1	Tip and ring EMI/EMC capacitors must be placed as close as possible to the phone connector RJ11.	
2	Ferrite beads must be placed as close as possible to the phone connector RJ11, must be after the surge protection device (commonly a sidactor).	
3	All TNV circuits must have a minimum of 106.3 mils (2.7 mm), 126 mils (3.2 mm) for medical, separation from all SELV circuits to meet international safety regulations with some margin (98.43 mils (2.5 mm) is absolute min). However for increased lightning surge protection to greater than 6 kV this clearance should be increased to 157.48 mils (4 mm) or 196.85 mils (5 mm).	
4	All PCB traces and pads connected to TIP shall have a minimum separation from all traces and pads connected to RING by a minimum distance of 20.08 mils (0.51 mm). This rule represents an absolute minimum requirement applicable to mobile designs such as MDC (very constrained PCB area). Of course, a larger clearance is acceptable and desirable, if the PCB area permits it.	

Table 44-2. General Routing Review Checklist

Item NO.	Description	Y/N
1	Sidactor shall be placed close to the telephone connector RJ11. The circuit traces connecting sidactor to RJ11 shall not be less than 25.2 mils (0.64 mm) wide. This minimum trace width ensures that the traces will survive lightning surge currents during metallic surge events.	
2	No VIA and no tracks in the other intermediate layers must be installed in the area between the RJ11 and the sidactor.	

§ §



45 Platform Power Sequencing Specification

This chapter provides the following information:

- Platform Power Sequence requirements for the Coffee Lake platforms
- Platform Voltage Rails Status in the different S-States/M-States
- Voltage Rail Sequencing Requirements

45.1 PCH_PWROK, SYS_PWROK and Other PWRGD Signal Generation

The power sequencing consists of multiple stages of power state transitions. During each stage, different VRs will be turned on through various control signals from the processor such as the SLP_SUS#, SLP_S4#, and SLP_S3#. In response, the platform will ramp the required voltage rails in the required order and then asserted the various powergood signals required by the processor and other platform components after the necessarily timing requirements have been met.

During G3/DSx-S5 transitions, the platform will need to generate the DSW_PWROK and RSMRST# signals. In this phase of the power up sequence, the DSW and Primary power well voltage rails are ramped to the processor.

During S5-S0 and DSx-S0 transitions, the platform will need to generate the PCH_PWROK and SYS_PWROK signals to the processor. In this phase of the power up sequence, the platform and CPU S0 rails are ramped up. [Figure 45-7](#) shows a high-level representative control signal and the powergood logic diagram for generating the PCH_PWROK and SYS_PWROK signals. This figure shows the recommended power-on sequencing flow steps from SLP_S4# de-assertion until PLTRST# de-assertion for the Coffee Lake platform.

The PCH_PWROK signal is expected to be asserted by the platform to indicate to the processor that all required CPU voltage rails are up and stable and that the processor may continue the boot sequence leading up to PLTRST# de-assertion, such as starting to turn on clocks and executing other internal pre-reset activities. Not all CPU rails are required to be ramped up by the time PCH_PWROK is asserted, such as some of the IMVP8 based rails like VCC, VCCGT, and VCCGTx, which will be ramped later on in the power sequence. SYS_PWROK is expected to be asserted by the platform to indicate that the system and all of its non-CPU components are ready for PLTRST# de-assertion. During power state transition to S0, the SYS_PWROK signal is the final platform controlled hardware gate before PLTRST# de-assertion. Platform designers may optimize when the SYS_PWROK signal is asserted with respect to the PCH_PWROK signal to help optimize overall boot latency, depending on system and component timing requirements.

45.2 Sequencing Interface Signals List and Power Rails

Figure 45-1. CFL Flow Diagram for SYS_PWROK/PCH_PWROK Generation

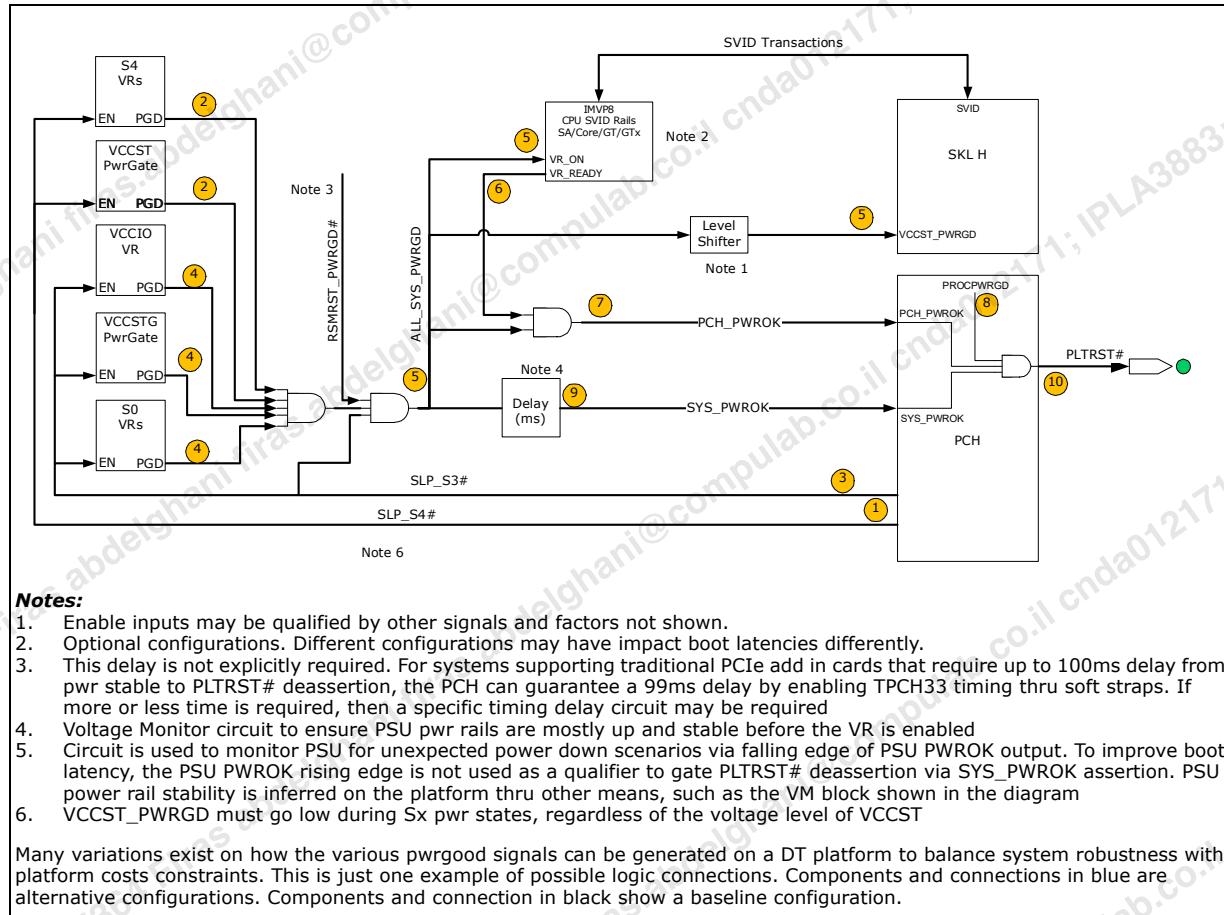
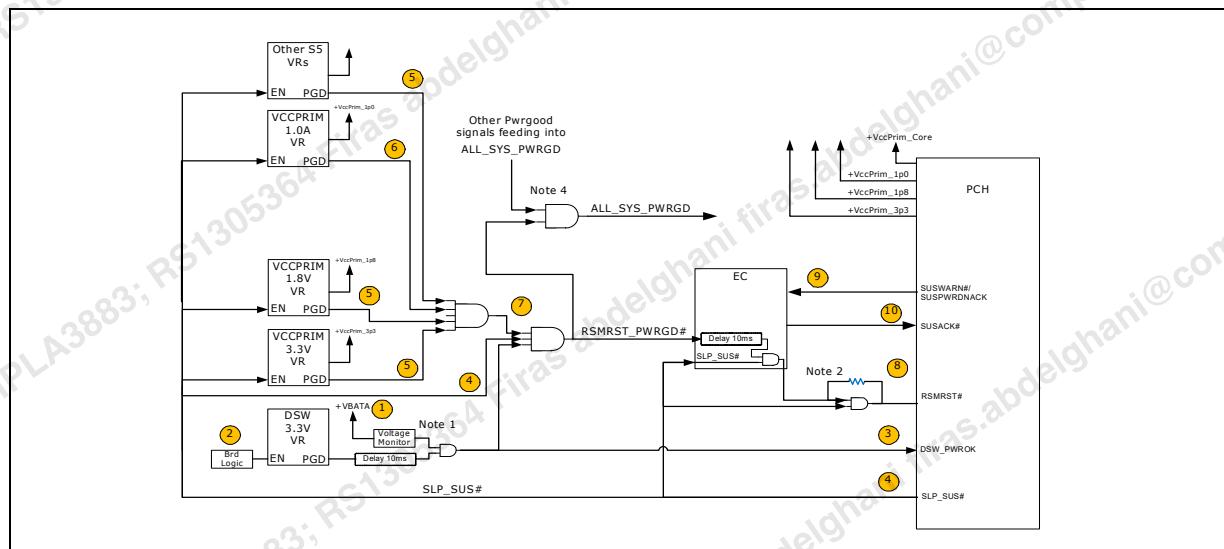


Figure 45-2. CFL Flow Diagram for RSMRST_PWRGD# Generation (Sheet 1 of 2)



**Figure 45-2. CFL Flow Diagram for RSMRST_PWRGD# Generation (Sheet 2 of 2)****Notes:**

1. This circuit is for early detection of surprise power loss to support proper RTC isolation. By monitoring the main input supply for abnormal behavior, DSW_PWROK can be de-asserted before VRs sourced from the main input supply start to shutdown or fallout of regulation.
2. NA
3. NA
4. Optional. Added for addition system robustness.
5. The reference configuration shown does not use EC. The system may or may not use SUSWARN and SUSACK# for handshaking with the PCH before exit from DSx.
6. Depending on response time of VR logic to assertion of SLP_SUS#, this may be optional. Refer to RSMRST# timing requirement (tPCH12).

Many variations exist on how the various pwrgood signals can be generated on a MB platform to balance system robustness with platform costs constraints and area constraints. This is just one example of possible logic connections. Components and connection in black show a baseline configuration, and components and connections in blue are alternative configurations. DSx configuration is shown.

Table 45-1. CFL Interface Signals List (Sheet 1 of 4)

Name	Source	Destination	Description
RTCRST#	Platform	PCH	When asserted, the signal resets the register bits in the RTC well.
SRTC RST#	Platform	PCH	The signal resets the manageability register bits in the RTC well when the RTC battery is removed
DSW_PWROK	Platform	PCH	Indication to the PCH that VCCDSW_3p3V rail is stable. For platforms NOT supporting Deep Sx this pin can be tied to RSMRST#.
RSMRST#	Platform	PCH	This signal is used for resetting the Primary power plane logic. This signal must be asserted for at least 10 ms after the Primary power wells are valid. When de-asserted, this signal is an indication that the power wells are stable.
SUSWARN#	PCH	Platform	This function is only applicable to platforms supporting Deep Sleep Wells. This pin asserts low when the PCH is planning to enter the Deep Sx power state and remove Primary power (using SLP_SUS#). The EC/motherboard controlling logic must observe edges on this pin, preparing for Primary well power loss on a falling edge and preparing for Prim well related activity (host/Intel ME wakes and runtime events) on a rising edge. SUSACK# must be driven to match SUSWARN# once the above preparation is complete. SUSACK# should be asserted within a minimal amount of time from SUSWARN# assertion as no wake events are supported if SUSWARN# is asserted but SUSACK# is not asserted. Platforms supporting Deep Sx, but not wishing to participate in the handshake during wake and Deep Sx entry may tie SUSACK# to SUSWARN#.



Table 45-1. CFL Interface Signals List (Sheet 2 of 4)

Name	Source	Destination	Description
SUSPWRDNACK	PCH	Platform	<p>This function is only applicable to platforms NOT supporting Deep Sleep Wells</p> <p>Asserted high by PCH when it does not require Primary well to be powered. No longer requires a 10-K pull-up to VCCSUS (3.3 V).</p> <p>This signal is required to be connected to EC for platforms with or without M3 support that do not support Deep Sx.</p> <p>This signal gives an added flexibility for the EC to turn OFF the Prim Rails when not needed by the PCH.</p> <p>SUSPWRDNACK can be High/Low in Sx/Moff based on the ME power policy selected.</p> <p>If platform doesn't support both Deep Sx and M3:</p> <p>EC must keep Prim rails powered ON if:</p> <p>SUSPWRDNACK is de-asserted low OR</p> <p>System state is S3</p> <p>Else, EC has the option to turn-off the Prim rails</p> <p>If platform doesn't support Deep Sx, but supports M3:</p> <p>EC must keep Prim rails powered ON if:</p> <p>SUSPWRDNACK is de-asserted low OR</p> <p>System state is S3 OR</p> <p>SLP_A# is de-asserted high OR</p> <p>It's the first 200 ms after Prim rails power has been applied</p> <p>Else, EC has the option to turn-off the Prim rails.</p> <p>Note: The polarity of SUSPWRDNACK is the opposite of SUS_WARN#. SUS_WARN# will assert low when Primary well power will be turning off, however SUSPWRDNACK will assert high when Primary well power can be turned off.</p>
SUSCLK	PCH	Platform	This clock is an output of the RTC generator circuit for use by other chips for refresh clock. SUSCLK is now moved to DSW (new on CFL).
ACPRESENT	Platform	PCH	Used on mobile systems to determine presence of AC power or battery power. In addition to previous Intel® ME to EC communication, PCH uses this signal to implement Deep Sx policies. For example, the platform may be configured to enter Deep Sx only on battery and not AC.
SUS_ACK#	Platform	PCH	<p>For platform supporting Deep Sx state, this signal is driven from the platform EC to PCH to acknowledge that EC has received the SUSWARN# signals and it is preparing to go into DeepSx mode.</p> <p>For non-DSW platforms, this signal can be left unconnected. Due to the internal pull-up on this signal it will be pulled high in order for the boot sequence to proceed. It does not matter if this assertion happens before or after SUSPWRDNACK assertion.</p>
SLP_SUS#	PCH	Platform	<p>For platforms supporting Deep Sx state, a low on this signal indicates that PCH is in Deep Sx state and that EC/platform logic does not need to keep the Primary Rails ON.</p> <p>If high means EC must keep Primary rails ON.</p> <p>If Deep Sx is not supported, then this pin can be left unconnected.</p>
PWRBTN#	Platform	PCH	Signal driven from EC to PCH indicating a system request to go into Sleep State OR if the system is already in the Sleep State then it will cause a wake event.
SLP_A#	PCH	Platform	This signal is used to control power to devices on the platform in conjunction with the Intel® ME sub-system. This signal will be asserted in M-off state. If M3 is not supported then SLP_A# will have the same timings as SLP_S3#.
SLP_LAN#	PCH	Platform	LAN Sub-System Sleep Control. Controls power to the LAN PHY. When "low", indicates that power can be shut off to the external wired LAN (GbE) PHY. SLP_LAN# will always be de-asserted in S0 and Sx/M3.
SLP_S5#	PCH	Platform	This signal is for power plane control. When asserted (low), it will shut-off power to all non-critical systems in S5 (Soft Off) states.

**Table 45-1. CFL Interface Signals List (Sheet 3 of 4)**

Name	Source	Destination	Description
SLP_S4#	PCH	Platform	S4 Sleep Control. This signal is for power plane control. When asserted (low), it will shut-off power to all non-critical systems in S4 (Suspend to Disk) or S5 (Soft Off) states.
SLP_S3#	PCH	Platform	S3 Sleep Control. This signal is for power plane control. When asserted (low), it will shut-off power to all non-critical systems in S3 (Suspend to RAM), S4 (Suspend to Disk) or S5 (Soft Off) states.
CL_RST#	PCH	Platform	This signal connects to the Wireless LAN device supporting Intel® AMT.
VDDQPWRGD	Platform VR	Platform Logic	Indicates that the DRAM power supply is stable and within specification.
Platform S0 Rails	Platform	Processor/PCH	These are all the non-core platform rails.
RSMRST_PWRGD#	Platform	Platform	The signal represents power good for VCCPRIM rails, 3.3V_DSW, and other S5 rails.
ALL_SYS_PWRGD	Platform	Platform	This signal represents the power good for all the non-core and non-graphics power rails.
IMVP VR_READY	Platform	CPU VR power circuitry	IMVP VR_READY is an active-high output that indicates the start-up sequence is complete, and the VR is ready to accept an SVID command and is operating properly. Refer to the VR_READY definition in the IMVP8 spec for additional details.
PCH_PWROK	Platform	PCH	When asserted, it indicates that all the main PCH Primary rails are up and all the main CPU rails (excluding VCC, VCCGT, VCCGTx, VCCOPC and VCCEPIO) are up.
SYS_PWROK	Platform	PCH	Generic power good input to the PCH is driven and utilized in a platform-specific manner. Informs PCH that power is stable to some other system component(s) and the system is ready to start the exit from reset (de-asserts PLT_RST# to the processor). Note: PCH_PWROK and SYS_PWROK both needs to be high to exit reset, but either signal can come up first. PCH does not monitor SYS_PWROK until after PCH_PWROK is asserted.
DRAM_RESET#	PCH	Processor	Controls reset to the memory subsystems, and is used on DDR3L, DDR4 (not applicable to LPDDR3).
PROCPWRGD	PCH	Processor	Indicates that VCCST, VCCSTG, VCCPLL, VCCPLL_OC, VCCIO, VCCSA, VDDQ (and for OPC SKUs, VCCOPC_1p8) power supplies and clocks are stable. This signal will be asserted only after PCH_PWROK assertion.
SUS_STAT#	PCH	Platform	This signal is asserted by the PCH to indicate that the system will be entering a low power state soon. This can be monitored by devices with memory that need to switch from normal refresh to suspend refresh mode. It can also be used by other peripherals as an indication that they should isolate their outputs that may be going to powered-off planes.
PLTRST#	PCH	Processor	The PCH asserts PLTRST# to reset devices on the platform (e.g., SIO, FWH, LAN etc.). Asserted during power-up and when S/W initiates a hard reset sequence through the Reset Control register.
SPI	PCH	Flash Device	Serial Peripheral Interface between PCH and BIOS Flash Device.
DMI	PCH	Processor	Direct Media Interface transactions between PCH and Processor.
SLP_WLAN#	PCH	WLAN	WLAN Sub-System Sleep Control: When SLP_WLAN# is asserted, power can be shut off to the external wireless LAN device. SLP_WLAN# will always be de-asserted in S0.
LAN_WAKE#	PHY	PCH	Can be used by the LAN PHY as a wake signal.
ESPI_RESET#	PCH	Platform	Controls reset to eSPI
VCCST_PWRGD	Platform	Processor	Indication that the VCCST\VDDQ power supplies are stable and within specification
DDR_VTT_CNTL	CPU	VTT VR	Enable signal for the DDR VTT VR
SLP_S0#	PCH	Platform	S0 Sleep Control. When PCH is idle and processor is in C10 state, this pin will assert indicate VR controller can go into a light load mode. This signal can also be connected to EC for other power management related optimizations.

**Table 45-1. CFL Interface Signals List (Sheet 4 of 4)**

Name	Source	Destination	Description
CPU_C10_GATE#	CPU	Platform	Power gating control to turn off VCCSTG, VCCIO and VCCPLL_OC in C10

Table 45-2. CFL Power Sequence Related Power Rails

Name	Source	Destination	Description
VCCRTC	Platform	PCH	3.05-V supplies for PCH RTC Well. This power is not expected to be shut off in any of the sleep states unless the RTC battery is removed or completely drained.
VCCDSW_3p3	Platform	PCH	3.3-V supply for Deep Sx wells. If Deep Sx is not supported on the platform, tie to VCCPRIM_3p3
VCCPRIM_1p0/1p8/3p3	Platform	PCH	PCH I/O and Misc rails 1.0/1.8/3.3V (Primary Well)
VCCSPI	Platform	PCH	1.8V/3.3-V supply for the SPI IO. This rail must be powered when VCCPRIM is powered.
VCC	Platform	Processor	Processor core rail
VCCST	Platform	Processor	Sustain voltage for processor in Standby modes
VCCPLL	Platform	Processor	CPU PLL power rails
VCCPLL_OC	Platform	Processor	CPU digital PLL power rails
VCCGT	Platform	Processor	Sliced graphics power rail
VCCGTX ¹	Platform	Processor	Unsliced graphics power rail
VCCIO	Platform	Processor	IO power rail
VDDQ	Platform	Processor	CPU Memory power rail, voltage dependent on memory technology
VPP	Platform	Processor	CPU Memory power rail, voltage dependent on memory technology
VCCSA	Platform	Processor	System Agent power rail

45.3 Power States

Table 45-3. System with M3 State Supported (Sheet 1 of 2)

Rails	S0/M0	S0ix/ M-off ¹⁶	S3/M3	S3/M- off	S4 & S5/M3	S4 & S5/ M-off	Deep S3	Deep S4/ S5	G3 ¹
RTC Well	ON	ON	ON	ON	ON	ON	ON	ON	ON
3.3V_DSW	ON	ON	ON	ON	ON	ON	ON	ON	No Power
VBATA (VDC)	ON	ON	ON	ON	ON	ON	ON	ON	No Power
V5.0A	ON	ON	ON	ON	ON	ON	OFF	OFF	No Power
V3.3A	ON	ON	ON	ON	ON	ON	OFF	OFF	No Power
V1.8A	ON	ON	ON	ON	ON	ON	OFF	OFF	No Power
V1.0A	ON	ON	ON	ON	ON	ON	OFF	OFF	No Power
V3.3M ³	ON	OFF	ON ¹¹	OFF	ON ¹¹	OFF	OFF	OFF	No Power
V1.8M ³	ON	OFF	ON ¹¹	OFF	ON ¹¹	OFF	OFF	OFF	No Power
VDDQ	ON	ON	ON	ON	OFF	OFF	ON	OFF	No Power
V2.5U	ON	ON	ON	ON	OFF	OFF	ON	OFF	No Power
VCCST ¹³	ON	ON	ON ¹⁹	ON ¹⁹	OFF ⁵	OFF ⁵	OFF	OFF	No Power
VCCPLL	ON	ON	ON ^{7, 19}	ON ^{7, 19}	OFF ⁵	OFF ⁵	OFF ⁵	OFF	No Power

**Table 45-3. System with M3 State Supported (Sheet 2 of 2)**

Rails	S0/M0	S0ix/ M-off ¹⁶	S3/M3	S3/M- off	S4 & S5/M3	S4 & S5/ M-off	Deep S3	Deep S4/ S5	G3 ¹
V3.3S	ON	ON	OFF	OFF	OFF	OFF	OFF	OFF	No Power
VCCPLL_OC ¹³	ON	OFF ¹⁷	ON ^{8, 19}	ON ^{8, 19}	OFF	OFF	OFF ⁸	OFF	No Power
VCC	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	No Power
VCCGT/VCCGTx	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	No Power
VCCIO	ON	OFF ¹⁷	OFF	OFF	OFF	OFF	OFF	OFF	No Power
VCCSA	ON	OFF ¹⁷	OFF	OFF	OFF	OFF	OFF	OFF	No Power

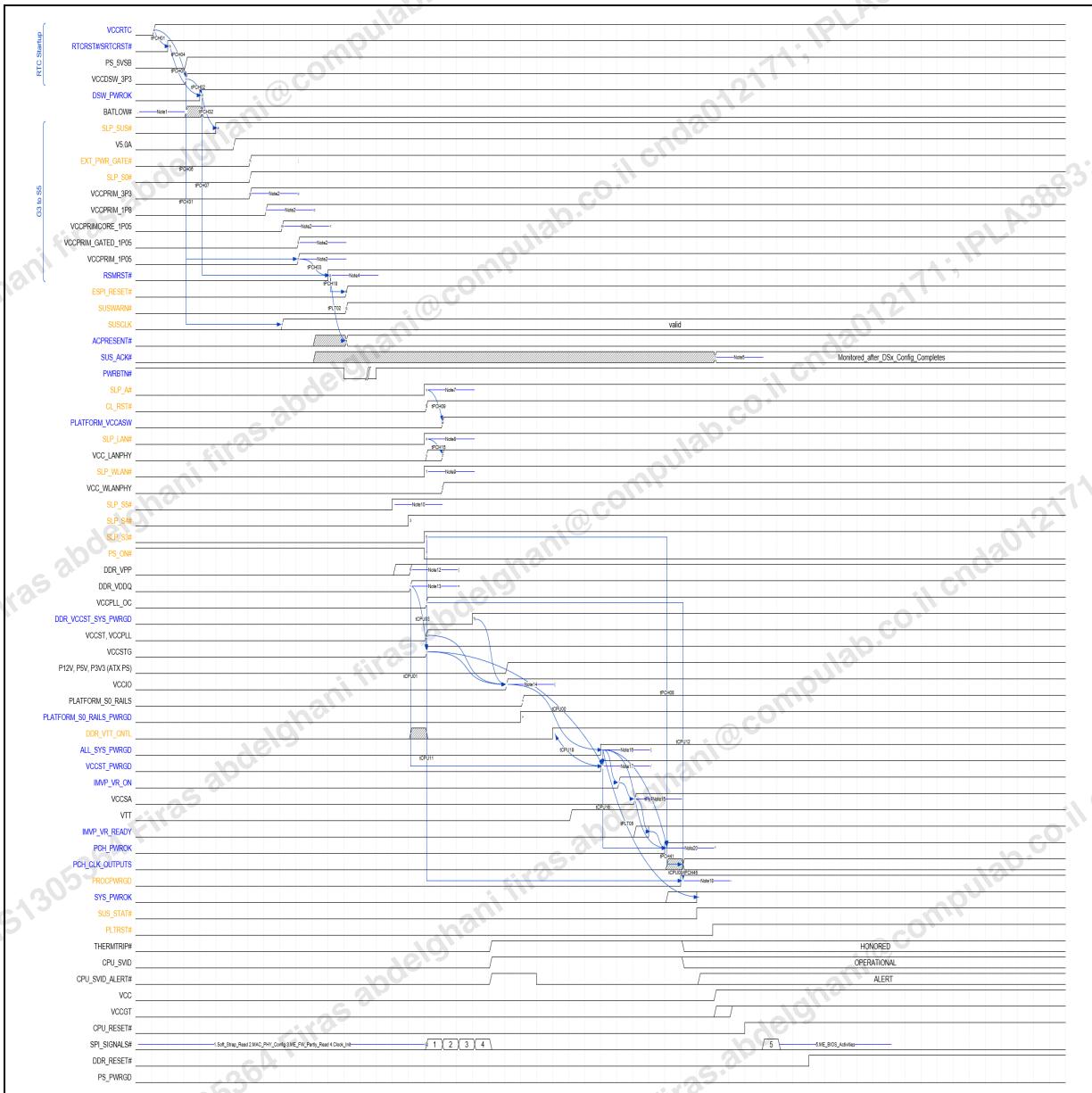
Notes:

1. The state of the system without RTC well powered can also be considered G3.
2. NA
3. V3.3M and V1.8M are platform rails used by external devices which ME operates during Sx/M3 states. These rails are not used directly by the CPU/PCH, and are not present on non-M3 supported systems
4. NA
5. VCCST, VCCPLL can remain powered during S4 and S5 power states for board VP optimization. VCCST may also remain powered in S4 and S5 for debug purposes. Refer to [Chapter 46, "Platform Debug and Test Hooks"](#).
6. NA
7. VCCPLL is allowed to be OFF in this power state, but it is generally assumed to be ON since it is powered from the same source as VCCST. VCCPLL should never be ON while VCCST is OFF
8. VCCPLL_OC is allowed to be turned off during S3 if it is not powered directly from VDDQ
9. NA
10. For no M3 support on external devices, V3.3M/V1.8M will be OFF in Sx/M3
11. VCCOPC_1p8 may be left on in Sx with minimal leakage.
12. NA
13. Assume SLP_S0# and CPU_C10_GATE# have asserted from the PCH. This supply is expected to be OFF during states where SLP_S0# is asserted. It may be left on during this condition, but the SoC will not achieve its lowest power consumption. Specific power up latencies apply when exiting this state. VCCST should be "on" whenever VCCPLL_OC is "on". VCCPLL_OC must be "off" whenever VCCST is "off", pay special attention particularly for systems supporting DS3.
14. For additional power savings in S3, refer [Section 45.5, "Additional Power Optimizations with Respect to VCCST Rail in S3"](#)

45.4 Power Sequencing Timing Diagrams—Legacy Signals

Table 45-4. Legend for Signals in Transition Waveforms

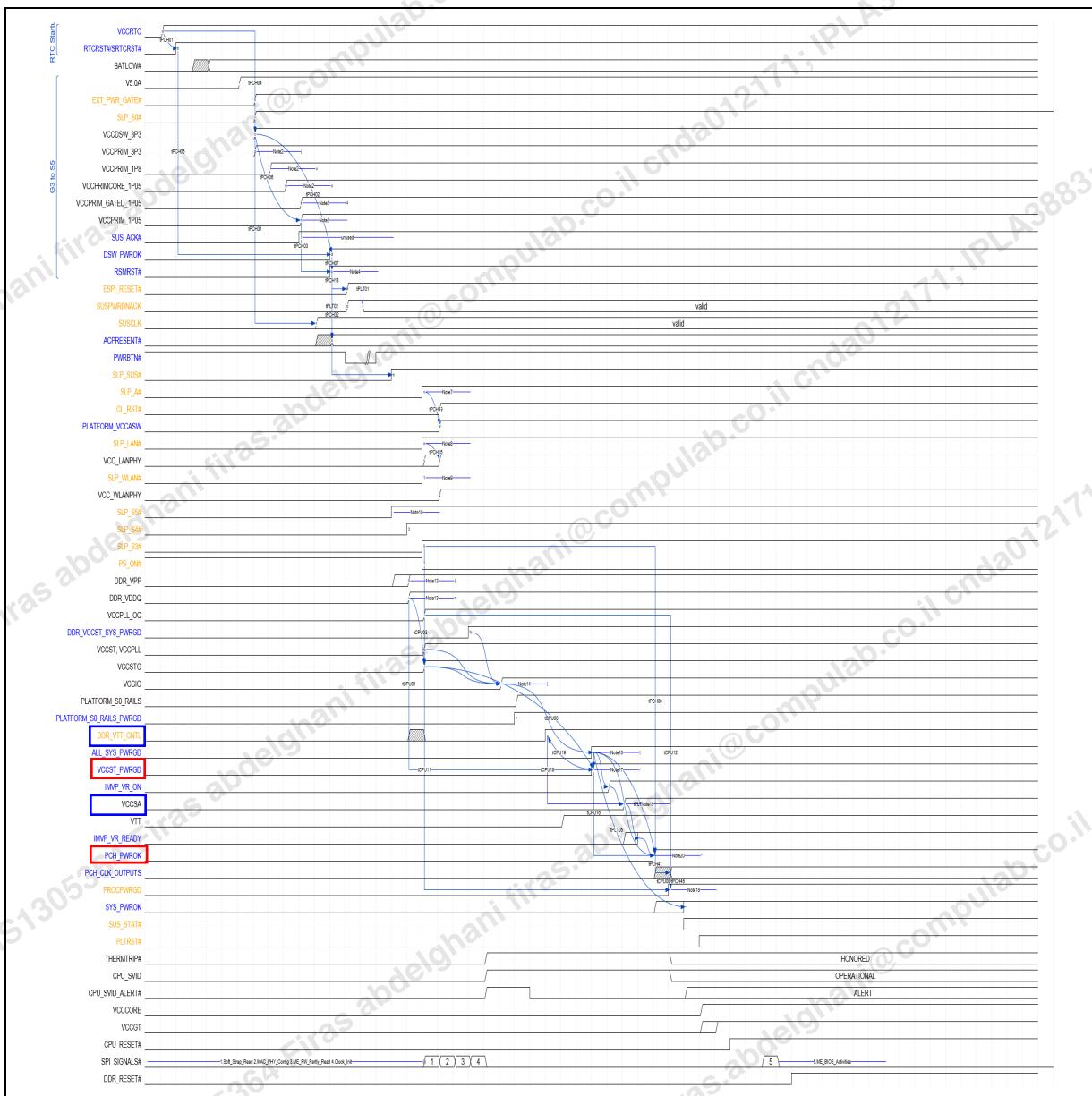
Color/Legend	Comments
Signal Names	Timing of these signals is set by PCH or processor
Signal Names	Timing of these signals should be met by the platform
Signal Names	Voltage rails or chip-to-chip buses
Grey Highlight	Indicates unstable state

Figure 45-3. Timing Diagram for G3 to S0/M0 [Deep Sx Platform] (Sheet 1 of 2)


**Figure 45-3. Timing Diagram for G3 to S0/M0 [Deep Sx Platform] (Sheet 2 of 2)****Notes:**

1. PCH will sample BATLOW# on the rising edge of DSW_PWROK for DSx Systems
2. Refer section TBD details on PCH prime rail-to-rail power and power down dependencies
3. For a DSx system, PCH will ignore SUSACK# until after SUSWARN# is valid
4. Minimum duration of PWRBTN# assertion = 16mS. PWRBTN# can assert before or after RSMRST#
5. On first exit from G3, SLP_A# de-asserts with SLP_S3# de-assertion
6. High for WoL=1, Low for WoL=0. SLP_LAN# may rise before, but no later than SLP_A#
7. On first exit from G3, SLP_WLAN# de-asserts with SLP_S3# de-assertion
8. Delay between SLP_S5#, SLP_S4#, and SLP_S3# exaggerated for drawing purposes. If the system EC is driving these signals in ESPI mode if the, the minimum delay between SLP_S3#, SLP_S4#, and SLP_S5# is not guaranteed
9. VCCST and VCCPLL can remain powered during S4 and S5 pwr states for board VR optimization. VCCST may also remain powered in S4 and S5 for debug purposes. Refer to debug port design guide for more details.
10. Only required with LPDDR3 and DDR4 memory configurations
11. VDDQ must ramp after VPP on DDR4 and LPDDR3 based systems, thus VDDQ may ramp up after SLP_S3# de-assertion due to VR ramp timing and configuration
12. VCCIO, VCCSA must ramp after VccST and VDDQ have completed their ramps.
13. IMVP VR_ON is recommended to be triggered by ALL_SYS_PWRGD in order to help minimize boot latency.
14. ALL_SYS_PWRGD is assumed to logically AND together the pwrgood signals for the major system power rails
15. VCCST_PWRGD can assert before or equal to PCH_PWROK, but must never lag it. It is recommended that both VCCST_PWRGD and PCH_PWROK include ALL_SYS_PWRGD and / or SLP_S3# in their generation. This ensures during failure events, both signals de-assert at the same time
16. NA
17. When "Power Button" is the trigger for wake or sleep event for the system
18. The Platform should ensure that PCH_PWROK does not glitch when RSMRST# is de-asserted
19. PS has a wide range of specifications, which may affect boot latency
20. Use of DDR_VTT_CNTL to control VTT power gate is optional for additional power savings in Idle power states. If not used, VTT should be controlled by SLP_S3#

Figure 45-4. Timing Diagram for G3 to S0/M0 [Non-Deep Sx Platform] (Sheet 1 of 2)



**Figure 45-4. Timing Diagram for G3 to S0/M0 [Non-Deep Sx Platform] (Sheet 2 of 2)****Notes:**

1. SLP_SUS# is ignored in Non-DSx systems
2. Refer section TBD for details on PCH prime rail-to-rail power and power down dependencies
3. For a non-DeepSx system DSW_PWROK and RSMRST# go high at the same time (connected on board)
4. For a non-DeepSx system SUS_ACK# will rise with prime voltage rail powering the VCCPGPPA power pin due to weak internal pull-up.
5. Minimum duration of PWRBTN# assertion = 16mS. PWRBTN# can assert before or after RSMRST#
6. On first exit from G3, SLP_A# de-asserts with SLP_S3# de-assertion
7. High for WoL=1, Low for WoL=0. SLP_LAN# may rise before, but no later than SLP_A#
8. On first exit from G3, SLP_WLAN# de-asserts with SLP_S3# de-assertion
9. Delay between SLP_S5#, SLP_S4#, and SLP_S3# exaggerated for drawing purposes. If the system EC is driving these signals in ESPI mode if the, the minimum delay between SLP_S3#, SLP_S4#, and SLP_S5# is not guaranteed
10. VCCST and VCCPLL can remain powered during S4 and S5 power states for board VR optimization. VCCST may also remain powered in S4 and S5 for debug purposes. Refer to debug port design guide for more details.
11. Only required with LPDDR3 and DDR4 memory configurations
12. **VDDQ must ramp after VPP on DDR4 and LPDDR3 based systems, thus VDDQ may ramp up after SLP_S3# de-assertion due to VR ramp timing and configuration**
13. **VCCIO, VCCSA must ramp after VccST and VDDQ have completed their ramps**
14. IMVP VR_ON is recommended to be triggered by ALL_SYS_PWRGD in order to help minimize boot latency.
15. ALL_SYS_PWRGD is assumed to logically AND together the pwrgood signals for the major system power rails
16. VCCST_PWRGD can assert before or equal to PCH_PWROK, but must never lag it. It is recommended that both **VCCST_PWRGD** and PCH_PWROK include ALL_SYS_PWRGD and / or SLP_S3# in their generation. This ensures during failure events, both signals de-assert at the same time
17. NA
18. When "Power Button" is the trigger for wake or sleep event for the system
19. The Platform should ensure that PCH_PWROK does not glitch when RSMRST# is de-asserted
20. PS has a wide range of specifications, which may affect boot latency
21. Use of DDR_VTT_CNTL to control VTT power gate is optional for additional power savings in Idle power states. If not used, VTT should be controlled by SLP_S3#

Additional Notes:

The state of the SLP_A# and SUSPWRDNACK signals are used by the EC to determine if PCH requires the suspend-well to stay powered.

- SUSPWRDNACK
 - *Platform not supporting M3* - EC must keep SUS Rails powered ON if: SUSPWRDNACK is de-asserted **OR** System state is S3. Else, EC has an option to do whatever it wants with the SUS Rails
 - *Platform supporting M3* - EC must keep SUS Rails powered ON if: SUSPWRDNACK is de-asserted **OR** System state is S3 **OR** SLP_A# is de-asserted **OR** it is the first 200mS after SUS Rails power has been applied. Else, EC has an option to do whatever it wants with the SUS Rails
- Primary rails and Deep Sx Rails should **never** be active while VccRTC rail is inactive.

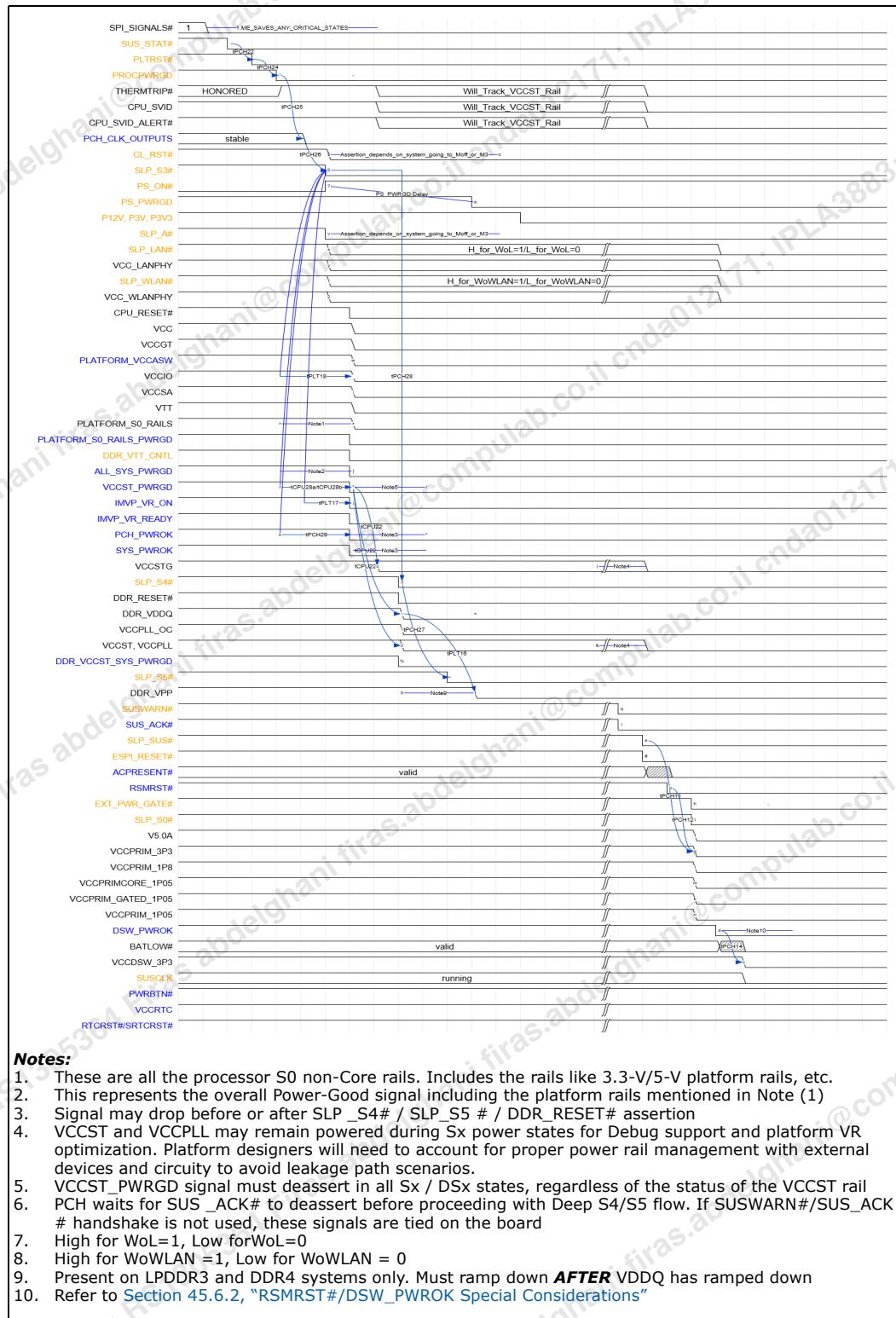
Figure 45-5. Timing Diagram for S0/M0 to G3 [Deep Sx Platform]




Figure 45-6. Timing Diagram for S0/M0 to G3 [Non-Deep Sx Platform]

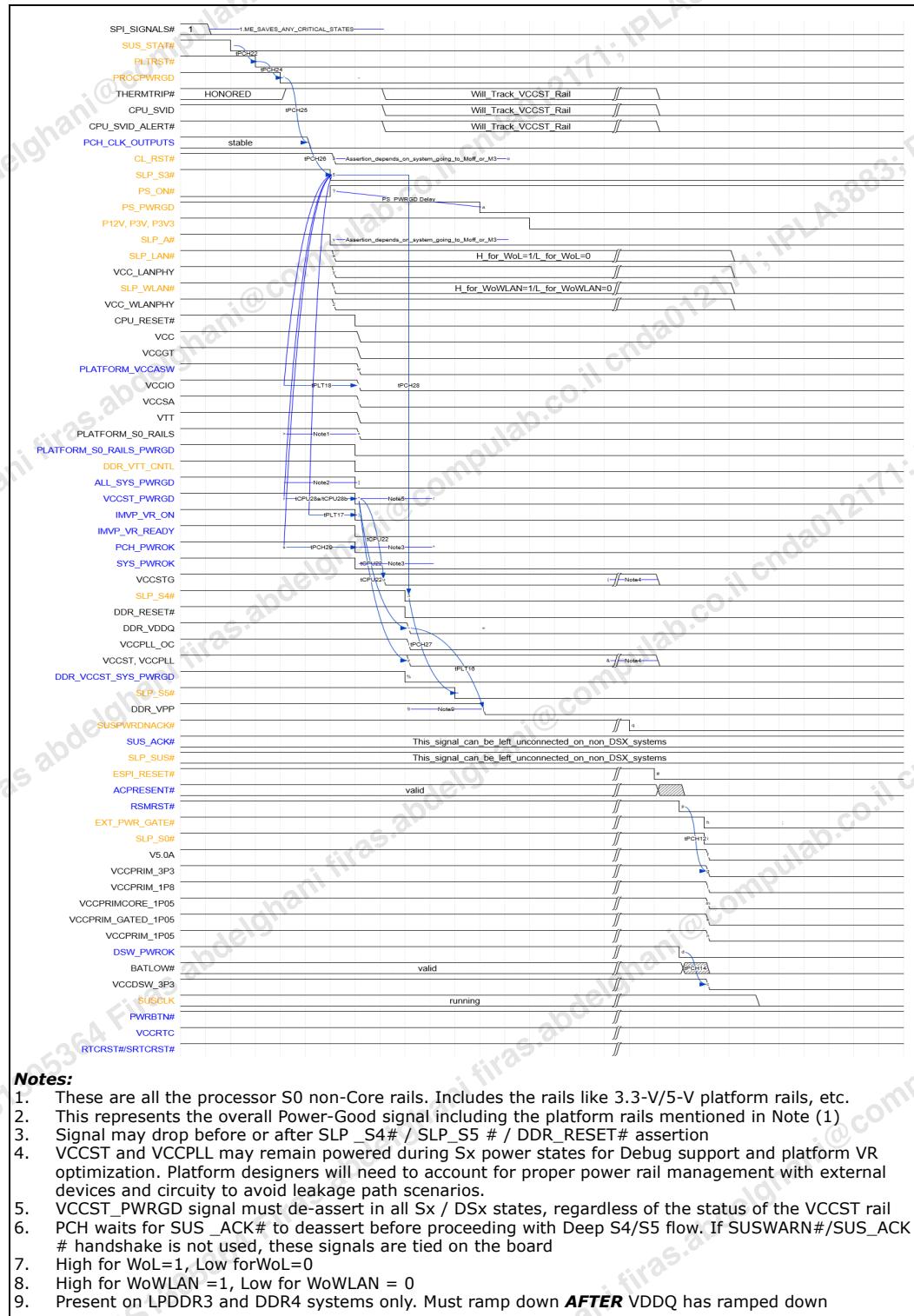


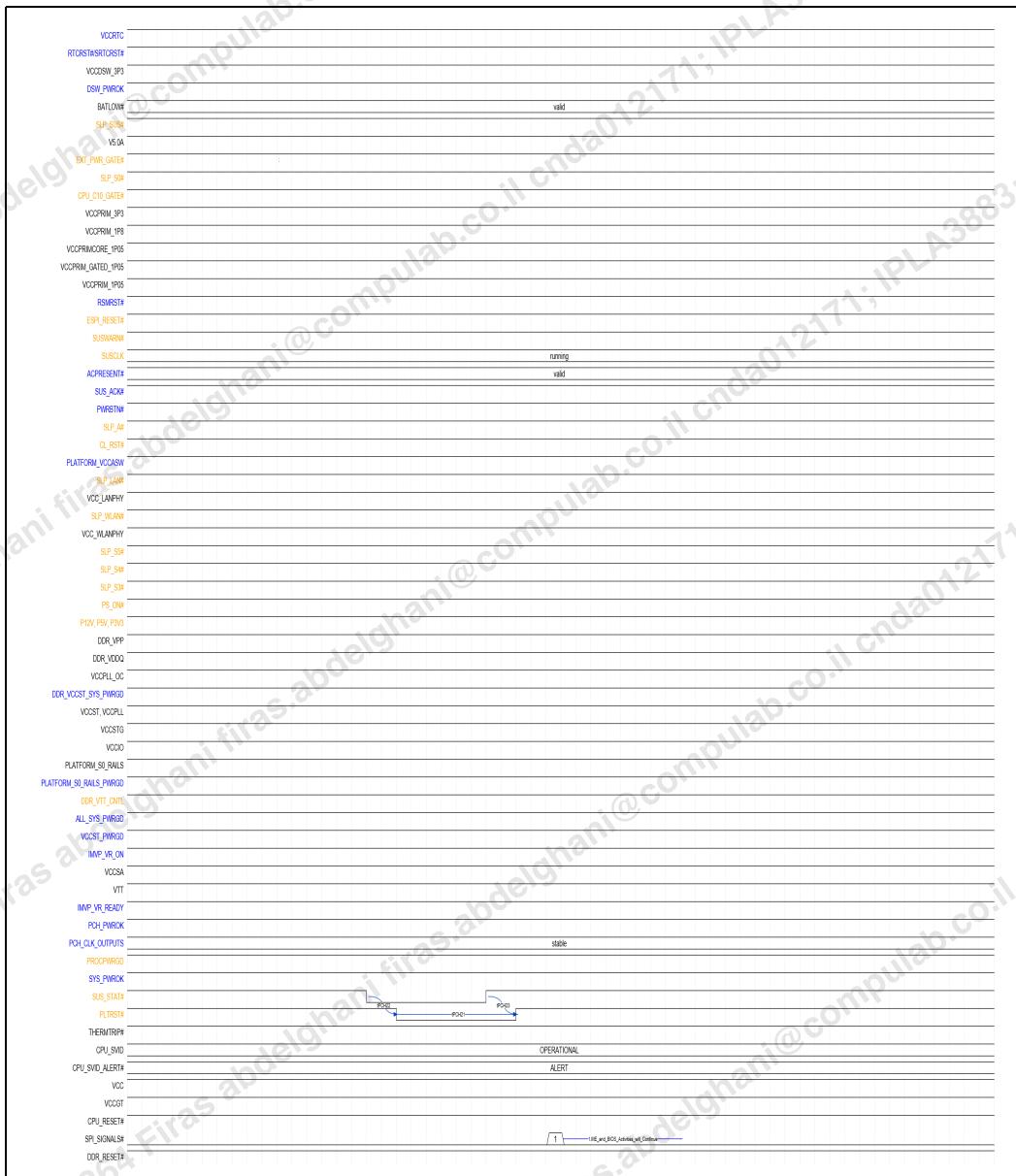
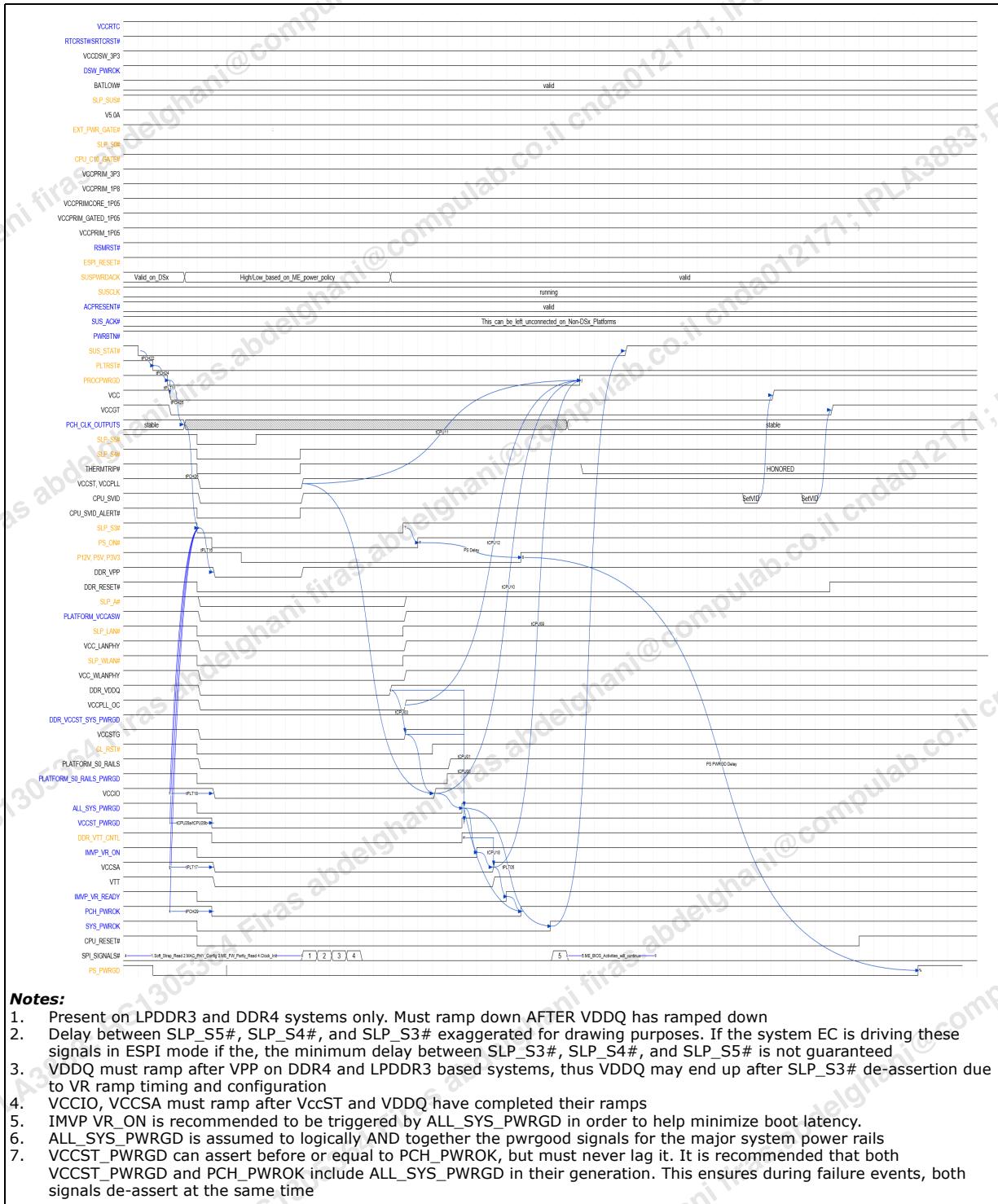
Figure 45-7. Timing Diagram for Warm Reset (Host Partition Reset w/o Power Cycle)




Figure 45-8. Timing Diagram for Cold Reset (Host Partition Reset w/ Power Cycle) and Global Reset [Non-Deep Sx Platform]





45.4.1 Power Sequencing Timing Requirements

The following table defines the timing parameters used in the timing diagrams in previous sections. The timing parameters are put into three categories: tCPU, tPCH, and tPLT. tCPU parameters are mostly required by the processor, tPCH parameters are required or controlled by the PCH, and tPLT parameters are mostly controlled by the platform.

Table 45-5. Platform Sequencing Timing Parameters (Sheet 1 of 7)

Label	Required By	Controlled By	Min.	Max.	Units	Note #	Description
tCPU00	CPU	PLT	1		ms	6, 7, 26	VCCST ramped and stable to VccST_PWRGD assertion
tCPU01	CPU	PLT	1		ms	6, 7	VDDQ ramped and stable to VccST_PWRGD assertion
tCPU02	CPU	PLT		No limit	ms	26, 43	VCCST ramped and stable before VDDQ stable Note: tCPU02 and tCPU03 are mutually exclusive, and only one of the parameters needs to be met depending on the rail order of VCCST/VCCSTG and VDDQ.
tCPU03	CPU	PLT		25	ms	26, 43	VDDQ ramped and stable before VCCST stable Note: tCPU02 and tCPU03 are mutually exclusive, and only one of the parameters needs to be met depending on the rail order of VCCST/VCCSTG and VDDQ.
tCPU04	CPU	PLT	0		ns	26, 31	VCCST must always ramp with or earlier than VCCSTG. VCCST >= VCCSTG at all times during ramp.
tCPU05	CPU	PLT	100		ns		VDDQ ramped and stable before VCCSA/VCCIO ramps
tCPU06	CPU	PLT	100		ns	27	VCCST ramped and stable before VCCSA/VCCIO ramps.
tCPU07	CPU	PLT	No Req	No Req	ns		VCCSA ramped and stable before VCCIO stable Note: this timing is to explicitly call out that there is no timing requirement between VCCSA and VCCIO.
tCPU08	CPU	PCH	1		ms	8	PCH CLK outputs stable and CPU VRs stable/ready to PROCPWRGD assertion
tCPU09	CPU	PLT	1		ms	23	VCCSA stable before PROCPWRGD
tCPU10	CPU	PLT	1		ms	23	VCCIO stable before PROCPWRGD
tCPU11	CPU	PLT	1		ms	23	VCCPLL stable before PROCPWRGD
tCPU12	CPU	PLT	1		ms	23	VCCPLL_OC stable before PROCPWRGD
tCPU16	CPU	PLT	0		ns	32	VCCST_PWRGD assertion to PCH_PWROK assertion
tCPU18	CPU	PLT	0	35	us	34	DDR_VTT_CNTL (was DDR_PG_CTL) assertion to DDR_VTT supplied ramped and stable while PLTRST = H (de-asserted).
tCPU19		CPU	0	100	ns	9	VccST_PWRGD assertion to DDR_VTT_CNTL (was DDR_PG_CTL) asserted.
tCPU20	CPU	PLT + PCH		500	ms	10	THERMTRIP# assertion until VCC, VCCGT, VCCSA, VCCIO VRs are disabled and not sourcing power.
tCPU21	CPU	PCH		1	ms		THERMTRIP# assertion until PCH issues global reset and assertion of SLP_SX signals

**Table 45-5. Platform Sequencing Timing Parameters (Sheet 2 of 7)**

Label	Required By	Controlled By	Min.	Max.	Units	Note #	Description
tCPU22	CPU	PLT	1		us		VCCST_PWRGD de-assertion to either VDDQ, VCCST below specification for normal S0 to Sx transitions. Recommend VCCST_PWRGD goes low with SLP_S3#.
tCPU23	CPU	PCH	TBD		us	45	PROCPWRGD de-assertion to either VCC* below specification for normal S0 to Sx transitions
tCPU26	CPU	PLT	10	65	us	11	CPU_C10_GATE# de-assertion to VCCSTG stable Note: CPU_C10_GATE# de-assertion to VCCST also needs to meet max 65us on cold boot
tCPU27	CPU	PLT	10	240	us	11	CPU_C10_GATE# de-assertion to VCCIO stable
tCPU28a	CPU	PLT		200	us	36	SLP_S3# assertion to VCCST_PWRGD de-assertion
tCPU28b	CPU	PLT	0		us	37, 38	VCCST_PWRGD low to VCCST dropping 5% of nominal value
tCPU29	CPU	PLT		100	mV/us	13, 25	Processor power rail instantaneous slew rate.
tCPU33	CPU	PLT		240	us	11	CPU_C10_GATE# de-assertion to VCCPLL_OC stable
tPCH01	PCH	PLT	9		ms	1, 47, 48	VccRTC = 2.0V to the point in time where voltage on the RTC resets equals 0.65 times the voltage present on the VccRTC rail during ramp. This measurement should be made from VccRTC = 2.0V to the first of RTCRST# or SRTCRST# reaching 0.65 * VccRTC
tPCH02	PCH	PLT	10		ms		VccDSW stable (@95% of full value) to DSW_PWROK high
tPCH03	PCH	PLT	10		ms		VccPrimary stable (@95% of full value) to RSMRST# high
tPCH04		PCH	9		ms	29, 42	VccRTC stable (@90% of full value) to start of VccDSW voltage ramp for systems with coined RTC battery
tPCH48		PCH	30		ms	29, 42	VccRTC stable (@90% of full value) to start of VccDSW voltage ramp for systems with coinless RTC
tPCH05	PCH	PLT	1		us	42	RTCRST# high (voltage above ViH_min) to DSW_PWROK high (when voltage crosses ViL_max such that internally it might be resolved as a logic '1')
tPCH06	PCH	PLT	200		us		VccDSW 3.3 stable (@95% of full value) to VccPrimary 1.05V starting to ramp (for DSx or nonDSx configurations)
tPCH07	PCH	PLT	0		ms		DSW_PWROK high to RSMRST# high
tPCH08	PCH	PLT	1		ms		SLP_S3# de-assertion to PCH_PWROK assertion



Table 45-5. Platform Sequencing Timing Parameters (Sheet 3 of 7)

Label	Required By	Controlled By	Min.	Max.	Units	Note #	Description
tPCH09	PCH	PLT	2, 4, 8, 16		ms		SLP_A# high to PCH assuming ASW rails are stable (95% of full value)
tPCH10	PCH	PLT	400		ns	4, 5	PCH_PWROK low to VCCIO dropping 5% of nominal value
tPCH11	PCH	PLT	100		ns		SLP_SUS# asserting to VccPRIM dropping 5% of nominal value
tPCH12	PCH	PLT	400		ns	5, 24	RSMRST# asserting to VccPRIM dropping 5% of nominal value
tPCH13	PCH		0		ms	14	RTCRST# asserting to VccRTC dropping 5% of nominal value (this applies only when RTC battery is removed)
tPCH14	PCH	PLT	400		ns	4, 5	DSW_PWROK falling to any of VccDSW, VccPrimary dropping 5% of nominal value
tPCH15	PCH	PLT		20	ms		SLP_LAN# (or LANPHYPC) rising to VccLANPHY high and stable
tPCH18	PCH	PCH	90		us		De-assertion of RSMRST# to De-assertion of eSPI_RESET# on exit from G3 (DSx platforms only), or exit from DSx
		PCH	95		ms		De-assertion of RSMRST# to De-assertion of eSPI_RESET# on exit from G3 (Non-DSx platforms only)
tPCH20	PLT	PCH	-100		ns		DDR_RESET# assertion to SLP_S4# assertion (The negative minimum timing implies that DDR_RESET# must either fall before SLP_S4# or within 100 nS after it).
tPCH21		PCH	Note 39		ms	39	Warm Reset PLTRST# assertion duration time
tPCH22		PCH	210		us		SUS_STAT# active to PLTRST# active
tPCH23		PCH	60		us		SUS_STAT# de-assertion to PLTRST# de-assertion
tPCH24		PCH	30		us		PLTRST# assertion to PROCPWRGD de-assertion
tPCH25		PCH	10		us		PROCPWRGD de-assertion to CLKOUT_BCLK turning OFF. This timing is programmable (Range = 10us, 100us, 1ms, 10ms). Default is set to 10 us.
tPCH26		PCH	1		us		CLKOUT_BCLK turning OFF to SLP_S3# assertion
tPCH27		PCH	30		us	33	SLP_S4# assertion to SLP_S5# assertion
tPCH28		PCH	30		us	33	SLP_S3# assertion to SLP_S4# assertion
tPCH29		PCH	0		ms		SLP_S3# assertion to PCH_PWROK deassertion
tPCH31		PCH		tPCH02 + tPCH32	ms	15, 44	VccDSW3p3 ramped and stable until SUSCLK is stable. SUSCLK will start before the max timing, but will not be guaranteed valid until max timing is met
tPCH32		PCH	95		ms		DSW_PWROK assertion to SLP_SUS# de-assertion (only applicable to Deep Sx supported platforms).

**Table 45-5. Platform Sequencing Timing Parameters (Sheet 4 of 7)**

Label	Required By	Controlled By	Min.	Max.	Units	Note #	Description
tPCH33		PCH	0, 99		ms	16	PCH_PWROK high to PLTRST# de-assertion. This timing is set by the PCH via Soft strap settings.
tPCH34	PCH	PLT		50	ms		All PCH Primary Rails should ramp up within this window.
tPCH35	PCH	PLT		100	ms	20	All PCH Rails should ramp down within this window.
tPCH36	PCH	PLT		100	mV/us		PCH Power rails instantaneous slew rate
tPCH37	PCH	PLT	5		mV/us	21	MPHY / SRAM Supply instantaneous slew rate
tPCH41	PCH	PCH	1		ms		PCH_PWROK high to PCH clock outputs stable
tPCH42	PCH	PLT		10	mV/us		VCCPRIM_Core slew rate during VID change
tPCH43	PCH	PLT	95		ms	28	DSW_PWROK assertion to PWRBTN# monitored
tPCH44	PCH	PLT	500		us		tPCH09 expiring to CL_RST# high
tPCH45		PCH	1, 5, 50, 100		ms	41	Clock outputs stable to PROCPWRGD assertion to processor. Timing set by PCH via Soft Strap settings
tPCH46		PCH	1, 2, 5		ms	41	PROCPWRGD and SYS_PWROK High to SUS_STAT# de-assertion. NOTE: Timing can be adjusted through the FIT tool
tPCH47	PCH	PLT	0		ms	46	RCIN# de-asserted to PCH_PWROK assertion
tPLT01		PCH	200		ms	2	RSMRST# de-assertion to SUSPWRDNACK valid. Timing set by PCH.
tPLT02			0	90	ms		RSMRST# de-assertion to ACPRESENT valid (not floating). NOTE: This is only for platforms not supporting Deep Sx state
				0	ms		RSMRST# de-assertion to ACPRESENT valid (not floating) [For platforms supporting Deep Sx state]. NOTE: ACPRESENT is a powered input to the PCH while in the Deep Sx state (that is, when DSW_PWROK=1 and RSMRST#=0). The PCH implements a weak pull-down on ACPRESENT while RSMRST#=0 such that the input is observed as 0 if not driven actively by the board during this time. If driven actively by the board to 1 while in Deep Sx and if the PCH is enabled to treat the ACPRESENT indication as a wake event from Deep Sx, then the PCH will power up the Primary well.
tPLT04	CPU/PCH	PLT	1		ms	3, 19	ALL_SYS_PWRGD assertion to PCH_PWROK. This timing must be controlled on the platform.
tPLT05		PLT	Platform dependent	No limit		18	ALL_SYS_PWRGD assertion to SYS_PWROK. This timing must be controlled on the platform. SYS_PWROK provides a platform/EC mechanism to stall the PCH de-assertion of PLTRST# to the platform. Different platform components may have different timing requirements from when their power rails are stable until their respective reset signal can de-assert. Platform designer should adjust this timing based on their specific platform requirements.



Table 45-5. Platform Sequencing Timing Parameters (Sheet 5 of 7)

Label	Required By	Controlled By	Min.	Max.	Units	Note #	Description
tPLT11	CPU	PLT		500	ms		SLP_S3# assertion to VCC, VCCGT, VCCIO and VCCSA <100mV.
tPLT14		PCH	4		s		Power cycle duration time; programmable via PM_CFG.PWR_CYC_DUR bit.
tPLT15	PLT (MEM)	PLT		200	us	40	SLP_S4# assertion to VDDQ EN Low (VDDQ VR disabled). Memory dependent, refer JEDEC requirements
tPLT16	PLT (MEM)	PLT	30		ms	30	VDDQ ramp down to start of VPP ramp down when entering S4 and lower. This is not SOC requirement but a recommended timing to help meet the JEDEC sequencing requirements. Platform designers are responsible for making sure their designs meet the power sequencing requirements for the memory technology used in their designs.
tPLT20	PLT (MEM)	PLT	2.5		ms	30	VPP ramped to VDDQ start of ramp when entering S0 at power up. This is not SOC requirement but a recommended timing to help meet the JEDEC sequencing requirements. Platform designers are responsible for making sure their designs meet the power sequencing requirements for the memory technology used in their designs.
tPLT17	CPU	PLT		200	us	35	SLP_S3# assertion to IMVP VR_ON de-assertion
tPLT18	CPU	PLT		200	us	35	SLP_S3# assertion to VCCIO VR disabled
tPLT19	PLT	PLT		10	us	22	RSMRST_PWRGD# or SLP_SUS# assertion to RSMRST# assertion

**Table 45-5. Platform Sequencing Timing Parameters (Sheet 6 of 7)**

Label	Required By	Controlled By	Min.	Max.	Units	Note #	Description
Notes:							
<ol style="list-style-type: none"> PCH Primary Rails must never be active while VCCRTC is OFF RSMRST# should be de-asserted for at least 200ms before PCH will consider SUSPWRDNACK valid. PCH can delay de-assertion of PLTRST# with a soft strap setting. Refer tPCH08 and tPCH09 and the SPI Programming Guide for more details. For catastrophic/surprise power failures only. For surprise power down cases, if DSW_PWROK is de-asserted (tPCH14) before DSW3.3 and any other Prim rails drop out of spec, there is no risk of RTC corruption (assuming VCCRTC was previously powered and VCCRTC# is de-asserted) and this spec can be ignored VCCST_PWRGD has no edge rate requirement, but edges must be monotonic. VCCST_PWRGD must accurately reflect the state of VCCST and must not glitch when VCCST, or VDDQ power is applied. Additionally, VCCST_PWRGD must track to the state of PCH_PWROK on the platform. When PCH_PWROK de-asserts during S0 --> Sx transitions, then VCCST_PWRGD must also de-assert. Processor's PROCPWRGD is not expected to be used externally on the platform, but is available for monitoring. CPU will assert DDR_VTT_CNTL after VCCST_PWRGD crosses its threshold point on rising edge, which will typically be around 0.5*VccST but can be anywhere between Vil to Vih levels. It is strongly recommended that the SLP_S3# be a qualifying input signal to ALL_SYS_PWRGD logic, which drives IMVP VR_ON inputs. Additionally, it is recommended that SLP_S3# also qualify the EN control to the VCCIO power supply NA NA Applies to all CPU power supply rails There are no perceived functional failures if this minimum is violated since all data is lost anyway when VccRTC drops. The only real requirement is to avoid driving a high signal level into the powered down device for an extended period of time, assuming an external device(s) on a different power supply than VCCRTC is driving RTRST# or any other RTC well input signal. SUSCLK is now powered in DSW well. PCH can delay de-assertion of PLTRST# with a soft strap setting. If tPCH33 is not enabled, the platform is responsible for controlling the assertion timing of PCH_PWROK and SYS_PWROK in such a way that it satisfies platform component timing requirements of power stable to reset de-assertion. Refer SPI Programming Guide for more details. On a platform level this timing doesn't necessarily need to meet 99ms, PCH soft straps guarantees a min of 99ms. NA Example, if the platform only has mini-PCIe* devices requiring a 1 ms delay from power rails stable to PCIe* reset de-assertion, then the minimum value for ALL_SYS_PWRGD assertion to SYS_PWROK can be reduced to 1 ms. If SYS_PWROK asserts before PCH_PWROK, no additional delay will be added by the PCH to delay PLTRST# de-assertion and the final timing value will be subject to internal PCH timing parameters. PCH_PWROK assertion assumes all the following CPU and PCH voltage rails are ramped and stable except for: VCC, VCCGT, VCCGTX, VCCOPC, VCCEOPIO No Ramp down requirement between rails. All VRs should stop regulation based on SLP_SUS# signal, or another common shutdown signal NA 10us max limit is an estimation and will vary based on platform VR and EC implementation details. Platform designers are responsible for ensuring that tPCH12 is not violated during normal DSx entries based on EC and VR response times to assertion of SLP_SUS# and/or RSMRST_PWRGD# PCH will have a minimum of a 1ms delay from PCH_PWROK to assertion of PROCPWRGD. Therefore, the platform is only responsible to have these rails ready a minimum of 0ms before PCH_PWROK assertion Applicable to all power down sequences where Prime well rails are turned off and to emergency power loss. Refer RSMRST#/DSW_PWROK Special Considerations section for more details. Only applicable to SKUs with OPC support If VCCSTG and VCCIO supplies are merged together as a single supply, then VCCSTG/VCCIO supply must also satisfy this requirement If VCCSTG and VCCIO supplies are merged together as a single supply, then the timing requirement is between VCCST/VCCSTG/VCCIO and VCCSA 							



Table 45-5. Platform Sequencing Timing Parameters (Sheet 7 of 7)

Label	Required By	Controlled By	Min.	Max.	Units	Note #	Description
Notes: (cont)							
28.							Applicable to all G3 exits where GEN_PMCON_B.AG3E=1. The PWRBTN# must assert for at least 16ms after the minimum tPCH43 timing before PCH will detect PWRBTN# as a wake event
29.							For scenarios where the coin-cell is dead or missing, the PCH can electrically tolerate the VCCRTC and VCCDSW/VCCPRIM 3.3V supplies ramping simultaneously with VCCDSW/VCCPRIM 3.3V leading VCCRTC by ~0.2 – 0.3V (i.e. voltage drop associated with the coin cell Schottky diode circuit). These scenarios are not allowed as typical power sequencing scenarios, and are expected to be very infrequent. In these scenarios, glitch-free signal operation on DSW signals can not be guaranteed when the platform is configured for DSx mode. Likewise, glitch-free signal operation on DSW and PRIM well signals can not be guaranteed when the platform is configured for non-DSx mode
30.							Generally, JEDEC specifications require VPP > = VDDQ for both power up and power down sequences. This timing parameter is a suggested value as ensure this requirement is met on power down, but systems designer must account for other platform level considerations such as output decoupling, discharge circuits, etc that can alter this relationship.
31.							VCCST supply is typically controlled by SLP_S4#, and VCCSTG supply is typically controlled by SLP_S0# AND SLP_S3#. Since the timing delay between SLP_S3# and SLP_S4# deassertion during a S4/S5 à S0 transition can be small (defined by tPCH28), OEMs may need to take extra steps to ensure this timing is met. Example, power gates of equivalent slew rate may be required on both VCCST and VCCSTG supplies. Alternatively, a small timing delay path might be required on the SLP_S3# path of the VCCSTG power gate enable
32.							VCCST_PWRGD should start to assert no later than when PCH_PWROK asserts; however, VCCST_PWRGD may lag completing its ramp with respect to PCH_PWROK by up to 20us
33.							Not applicable to eSPI mode, refer to the eSPI Compatibility Specification (RDC#508740) for eSPI implementations
34.							Only applies to configurations that use DDR_VTT_VCTRL signal to enable/disable VTT VR and only applies after PLTRST# has de-asserted (ie, S0). VTT must be completely ramped and ready for full load at or before the de-assertion of PLTRST# on Sx -> S0 transitions.
35.							Timing to VR being disabled, not until the VR is fully ramped down
36.							S0 to S3 transition with VCCST powered in S3 state
37.							S0 to Sx transition with VCCST unpowered in Sx
38.							Recommend not to exceed 200us delay with respect to SLP_S3#
39.							During a warm reset sequence, the PCH sequencing flows will internally re-execute several timing parameters and tPCH45 and tPCH46 are two of the parameters that are re-executed. tPCH45 and tPCH46 are primarily for G3/DSx/Sx -->S0 flows, but they are executed for cold boot, cold reset, and warm reset. The nominal setting for these timings is partially controlled by the setting of SPI soft straps associated with tPCH45 and tPCH46. The minimum possible PLTRST# assertion time will be equal to the soft strap settings for tPCH45 + tPCH46. The maximum PLTRST# assertion time is not guaranteed across all warm reset cycles, but the typical worst case assertion time is approximately equal to (tPCH45 soft strap setting) + (tPCH46 soft strap setting) + 20ms.
40.							This is a platform timing recommendation to help ensure that memory device power down sequencing requirements between VDDQ and VPP are likely to be met (refer tPLT16). This is not a requirement for the CFL SoC itself. Refer to the JEDEC LPDDR3 and DDR4 power down sequencing requirements for more details
41.							This parameter is programmable, refer to the Flash Descriptor Record in the SPI Programming Guide in the ME firmware package
42.							For the dead RTC coin cell and coin cell-less with depleted main battery RTC cases where the 3.3DSW ramps and powers the RTC well, the board designer should set the 3.3DSW rail stable to DPWROK assertion delay (tPCH02) for = 30ms. This is required to ensure that SRTCRST# and RTCRST# de-assert after VCCRTC is stable, but before DPWROK assertion. Failure to meet this requirement may result in DPWROK asserting with, or before, SRTCRST# and RTCRST# reach VIH, which is a sequencing violation and can result in a non-booting system scenario. Refer Section 30.2 (Real Time Clock Topology Guidelines) and Section 59.3.13 (RTC Circuit) for SRTCRST# and RTCRST# RC timing network details
43.							tCPU02 and tCPU03 are mutually exclusive, only tCPU02 or tCPU03 needs to be met
44.							SUSCLK stable means the clock is toggling and is within it's defined parameters. This timing spec is applicable to all G3 exits, excluding the G3 exit immediately following the ramp of VCCRTC, which may have a longer delay
45.							This does not concern platform design, this is internal to SOC.
46.							RCIN# is expected to be low in S3 and lower, but can be kept high in S3 through S5 without issue. RCIN# low in S3 and lower will not cause an INIT#. This requirement does not preclude the platform for asserting RCIN# after PLTRST# de-assertion when entering S0.
47.							C3 and C4 Capacitors used in the RTC external circuit should be evaluated with regards to aging, voltage and temperature characteristics to ensure reliable operation in the intended operating environment. See section 13.1.3 RTC External RTRST# Circuit.
48.							For measurement details, reference RTC Reset Timing Technical Advisory - RDC#610459.
Additional Notes:							
<ul style="list-style-type: none">Unless otherwise noted, all specifications in this table apply to all processor frequencies.DDR_RESET# behavior does not directly track the state of VDDQ rail. For DDR_RESET# to assert properly on surprise power failure, the VDDQ VR pwrgood output should be an input into the logic generating PCH_PWROK							



45.5

Additional Power Optimizations with Respect to VCCST Rail in S3

Throughout the PDG, it is generally noted that the VCCST rail should be ON during S3 power states, and is thus generally shown as being controlled directly or indirectly by the SLP_S4# signal. To save additional power during S3 power state, it is allowable to turn the VCCST rail OFF during S3 given that the following requirements and considerations are met. First, the following table below must be met. To support this table, an additional power gate would be required on the VCCPLL_OC in order to isolate this supply and turn it off during S3. Second, VCCPLL_OC must meet all the same timing requirements and rail-to-rail ramp requirements as VDDQ relative to all other rails of interest, specifically tCPU01, tCPU02, tCPU03 and tCPU05. All various figures and tables throughout the PDG such as in this chapter and other associated documents such as the Debug Port Design Guide and Coffee Lake Platform Power Design Guidelines will not be updated to explicitly reflect this option of turning VCCST off during S3. Also, it is assumed that VCCST and VCCPLL are supplied from the same power gate on the platform as documented in the Platform Architecture Guide, thus references VCCST in this description also include VCCPLL.

Table 45-6. Allowed VCCST and VCCPLL_OC Power State Combinations

VCCST	VCCPLL_OC	State
OFF	OFF	- VALID
OFF	ON	- INVALID
ON	OFF	- VALID
ON	ON	- VALID

Note: this table reflects valid and invalid power states for static, steady state conditions for leakage and long term reliability considerations

45.6

Rail-to-Rail Power Sequencing Requirements

45.6.1

Rail-to-Rail Sequencing For Various Supplies

The following diagrams show the recommended rail-to-rail sequencing requirement for Deep Sx configuration (Figure 45-3) and Non-Deep Sx configuration (Figure 45-4).

In general, Cannon Lake PCH architecture implements new capability to help minimize rail-to-rail sequencing related problems. As long as the RTC 3.3 V supply is powered up properly in advance of DSW and Primary rails, new isolation logic is active and will help achieve proper isolation between power rails during power up and power down sequences. The I/O interfaces will achieve proper isolation between the Primary 1.0 V supply and the higher 1.8 V and 3.3 V Primary / DSW supplies as well as achieving glitch-less I/O behavior for signals that support this capability.

During scenarios where the RTC supply is not powered such as a dead coin cell scenario and it is instead ramping along the Primary/DSW supplies through external platform circuitry, proper isolation between the Primary 1.0 V supply and the higher 1.8 V and 3.3 V Primary / DSW supplies cannot be guaranteed. It is thus possible that current inrush/back drive events could exist in these cases, but these scenarios are not a reliability risk to the PCH. It is, however, assumed that for general operation of Cannon Lake PCH, the RTC supply should be ramped and valid before the DSW and Primary rails ramp. Ramping the RTC supply simultaneously with the VCCDSW_3p3 rail for

Deep Sx systems and VCCPRIM_3p3/VCCDSW_3p3 rails for Non-Deep Sx systems as a standard power up sequence for every G3 exit is not a valid configuration and is not allowed.

Figure 45-9. CFL H Rail to Rail Sequencing Requirement for Deep Sx Configured System

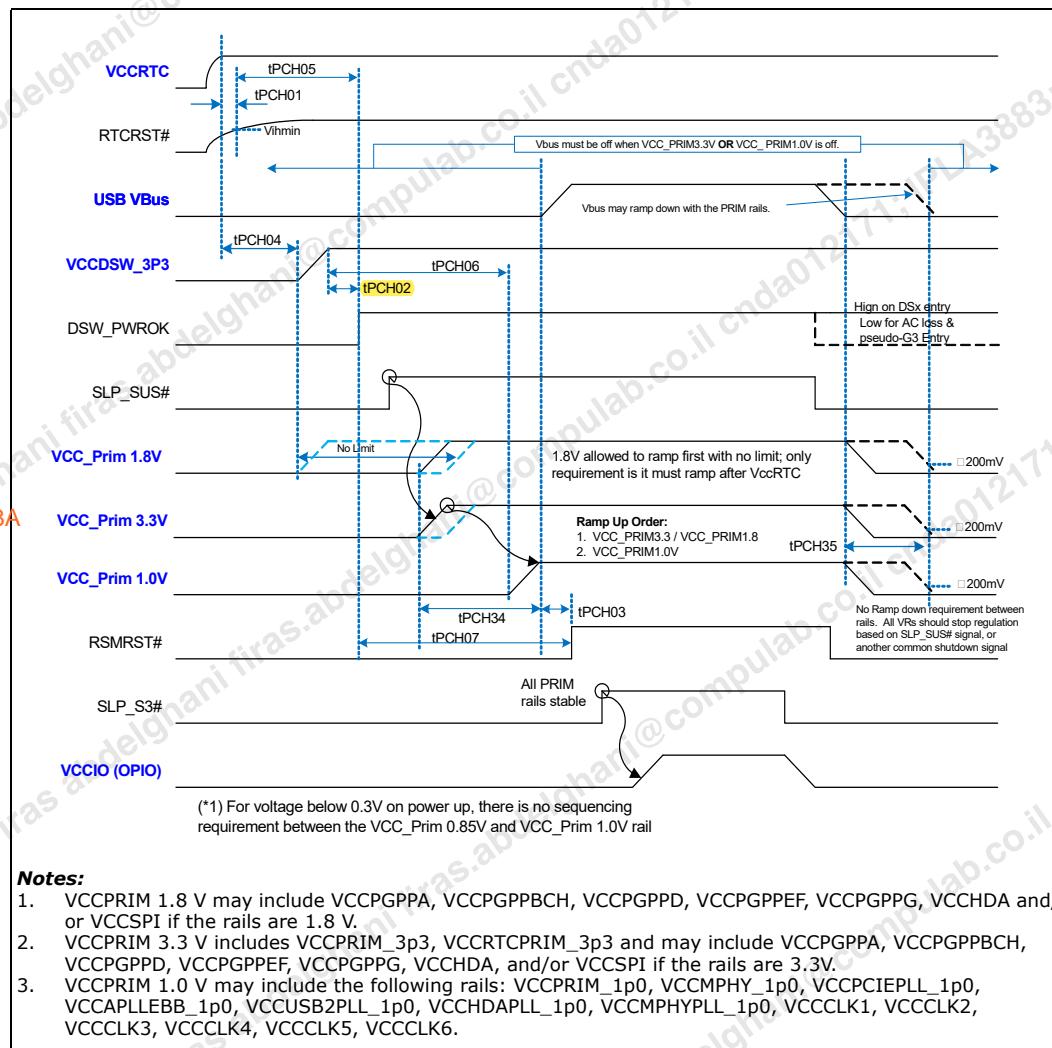
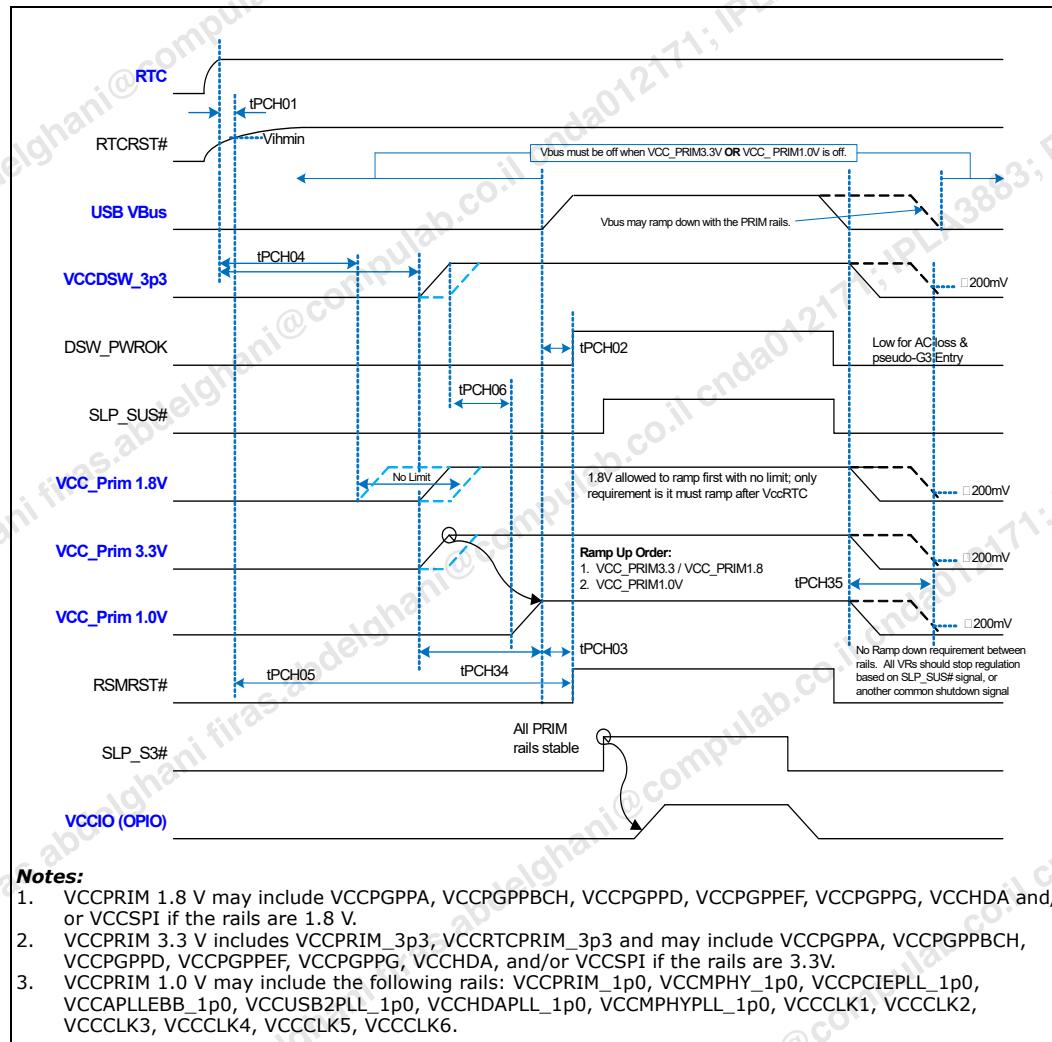




Figure 45-10.CFL H Rail to Rail Sequencing Requirement for Non-Deep Sx Configured System



45.6.1.1 General Rail-to-Rail Sequencing

For power up, all Primary rails should ramp within 50 ms of each other

For power down, there are no explicit timing requirements/relationships between the various Primary Well voltages on power down, but it is required that all Primary Well voltage regulators stop regulation simultaneously based on SLP_SUS# assertion. The power down sequencing should not be staggered from one VR to the next. Natural variance between VRs disabling due to differences in voltage regulator disable time is acceptable on the order of tens of microseconds. It is required that all rails ramp down within ~100 ms.

For surprise power down requirements, refer [Section 45.6.3](#) for assumptions.

**Table 45-7. Rail-to-Rail Sequencing Requirements**

Rail 1	Rail 2	Ramp Up	Ramp Down
VCC_PRIM 3.3 V/ VCC_PRIM 1.8 V	VPRIM_CORE/ VCC_PRIM 1.0 V	3.3 V Primary/1.8 V Primary rails ramp in advance of the 1.0 V Primary and VCCPRIM_Core rails	All rails must ramp down within 100 ms. Refer Section 45.6.1.1 .
VCC_PRIM_3p3/VCC_PRIM 1.0V	Vbus	Vbus ramp after VCC_PRIM 3.3V and VCC_PRIM 1.0V have both reached 95% of their final nominal voltage.	Vbus must ramp down with or before the PRIM rails.

Notes:

1. VCC_PRIM 1.0V may include the following rails: VCCPRIM_1p0, VCCSRAM_1p0, VCCMPHYAON_1p0, VCCMPHYGT_1p0, VCCMPHYPLL_1p0, VCCAPLL_1p0, VCCCLK1, VCCCLK2, VCCCLK3, VCCCLK4, VCCCLK%, VCCCLK6

45.6.1.2**Primary Rails and External USB Vbus Power Sequencing**

The Vbus provided to external USB ports can be used by USB devices to power their USB speed detect pull-up resistors. Some devices generate a local 3.3V power supply and pull up the D+ / D- lines with a 1.5k resistor. Other devices, per more recent USB ECRs, are allowed to pull up the D+/D- lines with Vbus voltage directly using ~7.5k resistor; implementation varies with device design.

If Vbus is powered while VCCPRIM_3p3 is not powered, and a device pulls either data line to 3.3V via its speed select pull-up resistor, the PCH will be exposed to leakage current through its un-powered USB 2.0 buffers. These leakage paths potentially impact both Non-Deep Sx and Deep Sx board designs alike.

The leakage paths exist only when Vbus is powered while VCCPRIM_3p3 and VCCPRIM_1.0V are both unpowered.

Powering Vbus while the PRIM rails are not powered is permitted, but designers should be aware that leakage through the PCH may occur.

45.6.2**RSMRST#/DSW_PWROK Special Considerations**

When the system is powered off (G3), DSW_PWROK and RSMRST# must not glitch from their Low states while the corresponding PCH rails are not powered or are below normal operating voltage specifications to ensure RTC corruption does not happen.

When a system is in S0-S5 state and not entering a Deep Sx or G3 state, the RSMRST# may only be driven low if the DSW_PWROK is also driven low (by an external controller such as EC). Failure to meet this requirement may result in unexpected PCH behavior, including failure to boot, which may only be recovered through a G3 cycling. This requirement does not apply to systems that tie the DSW_PWROK and RSMRST# together.

RSMRST# must always be driven low before any of the PRIMARY rails fall below the lower end of their tolerance band (Taking RSMRST low without taking DSW_PWROK low is not permitted when not entering DSx states). This is true for all power states transitions including emergency power loss.



45.6.3 Surprise Power Down Sequencing Considerations

Surprise power down events will be treated slightly differently on Cannon Lake PCH compared to past generation platforms. The main goal of the various power down timing specification such as tPCH10, tPCH12, tPCH14, etc., is to ensure proper isolation between the associated power well and the RTC well to guarantee that RTC contents are not accidentally corrupted. There are many events that could cause a surprise power down. The following is a short list of some events, but is not exhaustive:

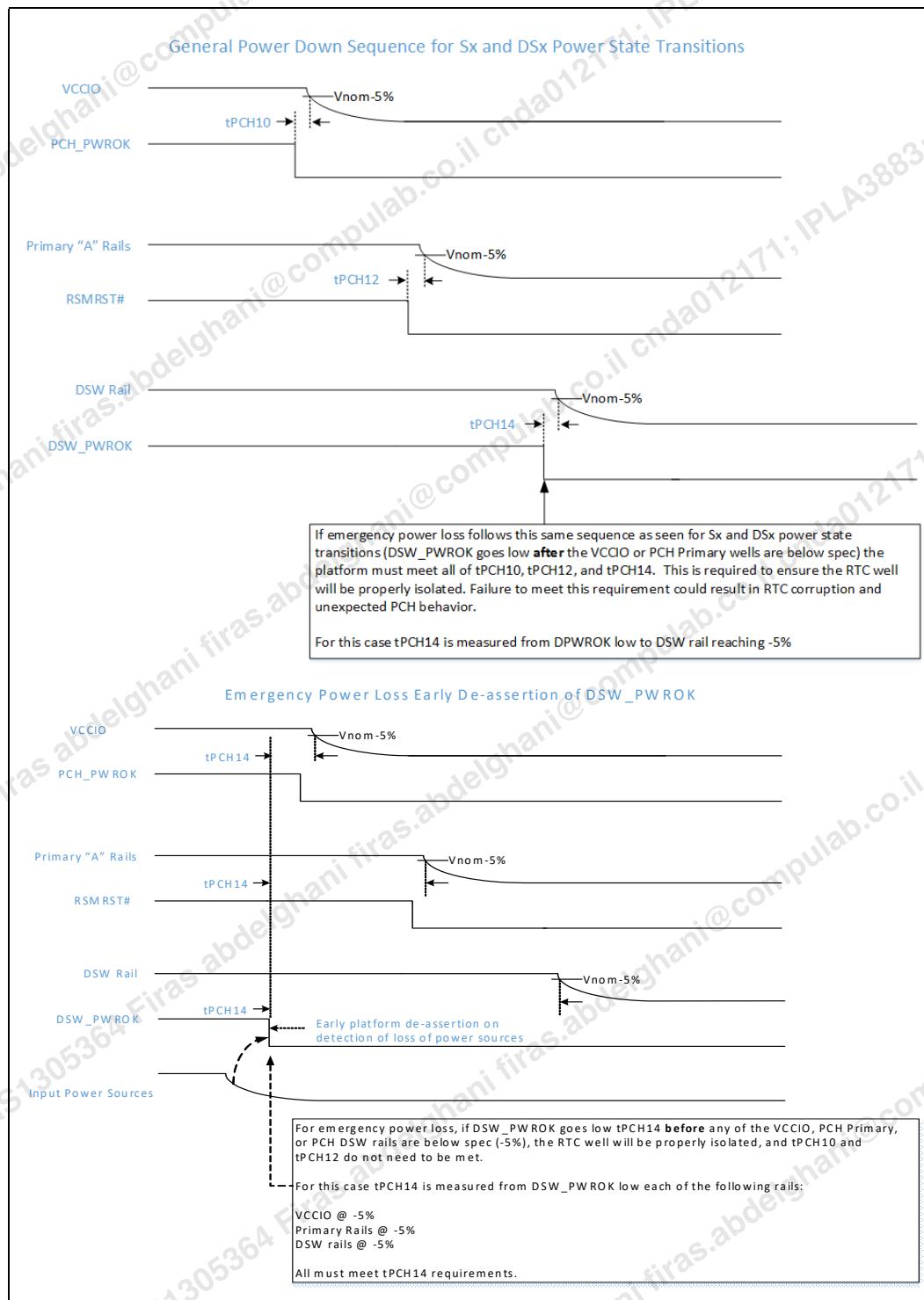
- VR failure (over current, overvoltage, IC failure, etc.)
- AC removal with no DC Battery present
- Removal of the primary battery

Properly designed platforms generally should not be experiencing VR failures of any kind; therefore the focus of this section is on the unexpected power removal caused by user interaction, which could be an end user, factory technicians, etc.

To ensure RTC is not corrupted, the platform must de-assert the appropriate power good signals BEFORE the rails go out of their defined tolerance range. This implies that the platform should monitor the highest voltage available which is usually the main power supply like the battery voltage to determine when it has dropped too low and VR failure/shutdown is eminent. At that point, the PCH power good signals (PCH_PWROK, RSMRST#, DSW_PWROK) should be driven Low before their associated rails turn off and droop below the defined tolerance. Note, for these cases, de-assertion of just the DSW_PWROK signal is sufficient to activate isolation logic for ALL power wells, thus guaranteeing RTC corruption cannot happen.

Refer Figure 45-7 below for more details.

Figure 45-11.DSW_PWROK Requirement for Power Loss





45.6.4 eSPI Considerations for Sequencing

In general, eSPI support does not have any major impact to power sequencing requirements. However, there are a few behavioral differences worth noting that could have side effects to platform behavior that should be considered.

With eSPI, the EC may or may not take in or drive physical pins that historically would have been supported by the PCH. The values of these signals (ex. SLP_S4#) are tunneled over the eSPI interface between the PCH / EC like virtual wires. If the EC is driving the physical version of these virtual wire signals instead of the PCH driving the signal natively, the PCH cannot guarantee the timing relationships between various tunneled sequencing signals is maintained due to inherent bus latencies.

Only the physical signals directly on the PCH are guaranteed to refer the PCH-defined timing relationships. Example, SLP_S4# de-assertion → SLP_S3# de-assertion relationship is defined as 30 us for the physical pins but could be shorter for the virtual wire relationship on the EC.

45.6.5 Virtual wire SUSWARN deassertion delay during global reset

1. For eSPI enabled platforms, the platform SUS_WARN# de-assertion can occur much later compared to LPC based previous platforms.
2. Hence it is recommended that eSPI based platforms should account for at least 5-6 seconds of delay between eSPI_RESET# de-assertion and SUSWARN# eSPI VW de-assertion from SoC/PCH to EC.
3. This additional delay between above mentioned PCH signals is applicable for Global reset flows only but not for G3 exit flows (or) Sx cycles which do not have the long delay between eSPI_RESET# and SUSWARN.
4. Note that the behavior above does not change the total time for Global reset exit.

§ §

46 Platform Debug and Test Hooks

Intel is committed to reducing debug time and cost for OEMs and system integrators. Many debug features and test hooks have been designed into the platform to help reduce these factors. The following section provides implementation details of the processor debug and test hooks specifically to this platform only and takes priority over any discrepancies existing between this document and any previous Debug Port Design Guide.

The details of this chapter are requirements for run control (XDP) debug-port design and Intel Direct Connect Interface (DCI), unless the text explicitly states that a design rule or connection is optional. Note that while this content provides design solutions to allow both run control tool and boundary scan test JTAG tool to utilize the same JTAG scan chain for debug and manufacturing testing respectively, it does not contain all of the routing and design requirements for use with a boundary scan JTAG tool. Please contact your Intel Field Representative if additional information on manufacturing boundary scan testing is needed.

Note:

The resistor values used for the JTAG signals in this content are meant for ITP or Run control JTAG debugger only and are subject to change according to test/debug tool condition. For example, some third party JTAG test tools may not have enough drive strength to meet the input-threshold requirements of the Intel Silicon with the strong 50- Ω terminations required for the ITP debugger.

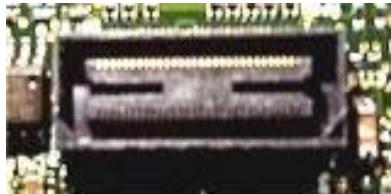
The Coffee Lake JTAG (TAP) ports are compatible with the IEEE Standard Test Access Port and Boundary Scan Architecture 1149.1 and 1149.6 Specification, as detailed per device in each BSDL file.

In this chapter, the term ITP and ITP-XDP can be interchanged with run-control tool or halt-mode debugger. Intel works with several run-control vendors to create tools that can be used if the guidelines within this document are followed. Please contact your Intel representative to obtain the list of tool vendors.

46.1 Platform Debug Port Options

Table 46-1 describes the two connector options and Table 46-2 describes the two JTAG based debug hook routing options for Coffee Lake platforms:

Table 46-1. Coffee Lake Run Control Tool Debug Port Options (Sheet 1 of 2)

Debug Port Connectors	Figure/Diagram
60-pin eXtended Debug Port (XDP) connector The XDP target system connector is a Samtec [*] 60-pin BSH-030-01 series connector. Specific plating types, locking clips, and alignment pins versions of this connector can be obtained from Samtec TM . No specific plating types, locking clips or alignment pins are required for the XDP tool. Refer Section 46.1.4 for 60-pin XDP Mechanical Specification	

**Table 46-1. Coffee Lake Run Control Tool Debug Port Options (Sheet 2 of 2)**

Debug Port Connectors	Figure/Diagram
<p>Chassis Mount Connector (CMC)</p> <p>CMC is a compact connecting solution developed by Intel for Coffee Lake platform debug. CMC has a much smaller keep-out than the standard 60 pin XDP connector. It utilizes a motherboard through-hole for mounting and makes contact with pads located and routed around the mounting hole via the CMC connector. There are two versions of CMC adapters: the CMC Merged adapter (primary CMC) offers the same DFX accessibility (with the exception of SMBus), HOOK[2,3,4,5,7]) as the standard 60-pin XDP connector and the CMC OBS adapter (secondary CMC) provide access to PCH OBS signals via paddleboard.</p> <p>Refer Section 46.1.5 for CMC Mechanical Specifications</p>	<p>Primary CMC Debug Solution:</p> <p>The diagram illustrates the primary CMC debug solution. An XDP Probe (Note 6) is shown in red, connected to a CMC Adapter. The CMC Adapter is mounted on a Mother Board. A callout bracket groups the XDP Probe and the CMC Adapter, with the label "CMC Adapter" pointing to the adapter itself. The Mother Board is indicated by a green arrow pointing to the board below.</p> <p>Secondary CMC Solution:</p> <p>The diagram illustrates the secondary CMC solution. A CMC Adapter is shown mounted directly onto a Mother Board. A callout bracket groups the CMC Adapter and the Mother Board, with the label "CMC Adapter" pointing to the adapter.</p>
<p>Intel Direct Connect Interface (DCI)</p> <p>Intel® Direct Connect Interface (DCI) is a new Intel debug tool-transport technology that connects the host system to the System-Under-Test (SUT) using the USB3 port. The advantage is debug functions and trace features can be connected using existing USB3 ports, rather than the usual additional connectors. This enables easy connections to production systems where debug connectors have been removed.</p>	

**Table 46-2. Run Control Debug Hooks Routing Options**

Routing Options	Links to Guidelines	Use Cases
Option 1 (preferred/recommended): One primary debug port (either a 60-pin XDP or a CMC) for Coffee Lake's JTAG, CFG[0:19], System control, power and ground signals: <ul style="list-style-type: none">Support only dual TCK scan chain (aka Shared JTAG) design for the CPU and PCH components. and, One secondary debug port (either a 60-pin XDP or a CMC) for PCH Chipset Test Interface signals.	<ul style="list-style-type: none">Refer Section 46.1.1.1 for detail routing guidelines for the Dual TCKs scan chain only topology.Refer Section 46.1.1.2 for CFG[19:0], PROC_PREQ#, PROC_PRDY# and BPM#[1:0] routing guidelines.Refer Section 46.1.1.3 for Primary XDP System Control signals, Power and Ground pins routing guidelines.Refer Section 46.1.2 for detail routing guideline of Secondary Debug Port connector.Refer Section 46.1.4 for 60-pin XDP Mechanical SpecificationRefer Section 46.1.5 for CMC Mechanical Specifications	<ul style="list-style-type: none">Used for closed chassis debug through the USB port using an Intel® SVT Closed Chassis Adapter (CCA):<ul style="list-style-type: none">support processor run controlsupport Intel® AET/IOT tracingsupport Sx state/ME debugsource level debugMight support Intel® Silicon View Technology (Intel® SVT) based HVM manufacturing test solution. Refer with your HVM test tool vendor.Used for open chassis debug using an ITP or similar JTAG debugger,<ul style="list-style-type: none">support processor run controlsupport Intel® AET/IOT tracingsupport Sx state/ME debugsource level debugsupport Intel® Silicon View Technology (Intel® SVT) based HVM manufacturing test solution. Refer with your HVM test tool vendor for the exact tool usage model.Used for Intel® Silicon View Technology (Intel® SVT) based HVM and boundary scan manufacturing testing. <p>Note: This is the preferred debug port routing options on most boards. CMC is recommended for use as secondary debug port because it requires less routing onboard and takes up less board space. Refer with your Intel representative if your HVM test tool required a Single Scan Chain (aka Common JTAG) support. Most Intel enabled JTAG test tool can support dual scan chain topology.</p>
Option 2: Intel Direct Connect Interface (DCI) over existing USB port Bare minimum routing with no connector on board.	Refer Section 46.1.3 for connector less routing requirement. and specification (Add in reference to Intel DCI section)	<ul style="list-style-type: none">Can only support closed chassis debug through the USB port using an Intel® SVT Closed Chassis Adapter. (Refer above for features)Used for Intel® Silicon View Technology (Intel® SVT) based HVM and boundary scan manufacturing testing <p>Note: Intel does not recommend this option for development board. It should only be considered for board that does not have board space to route traces to a primary CMC connector or for a production board when debug is no longer needed. Intel strongly recommends placing at least a primary CMC on the board.</p>

46.1.1 Primary Debug Port Debug Port Routing Guidelines

Unless otherwise indicated, routing guidelines in this section apply to both primary XDP and primary CMC connectors.

46.1.1.1 Primary Debug Port: Dual JTAG Scan Chain Only Topology

JTAG Topology in this section supports only Dual TCKs Scan Chain (aka Shared JTAG) covering the CPU and PCH components. This is a typical JTAG routing for Coffee Lake Platforms. This topology can not support HVM test tool or any JTAG debugger that requires both processor and PCH JTAG in a single scan chain that is controlled by the same TCK.

Refer with your Intel representative and your HVM tool vendor if your HVM test tool required a Single Scan Chain (aka Common JTAG) support.

Note:

The resistor values used for the JTAG signals in this content are meant for ITP or Run control JTAG debugger only and are subject to change according to test/debug tool condition. For example, some third party JTAG test tools may not have enough drive strength to meet the input-threshold requirements of the Intel Silicon with the strong 50- Ω terminations required for the ITP debugger. Consult with your test tool vendor for the appropriate resistor value to use.

Figure 46-1. Primary Debug Port-JTAG Topology for Dual Scan Chain Only Design

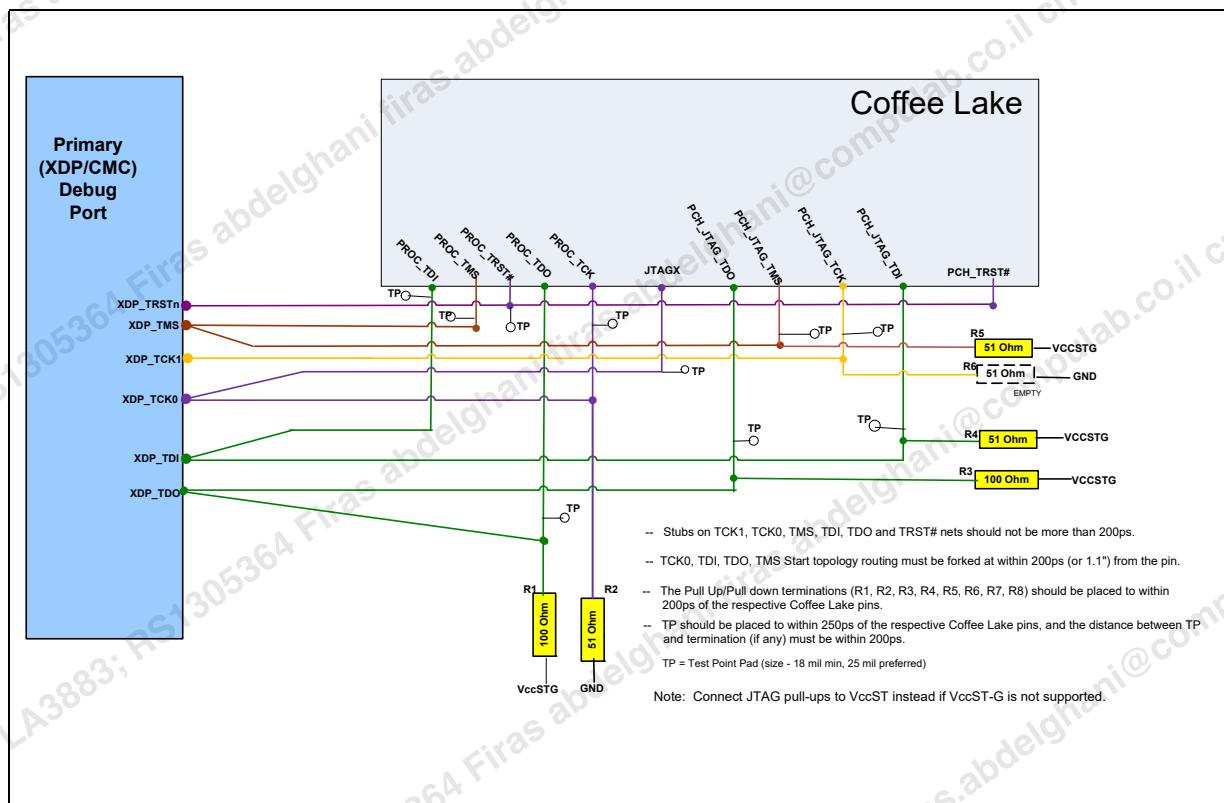
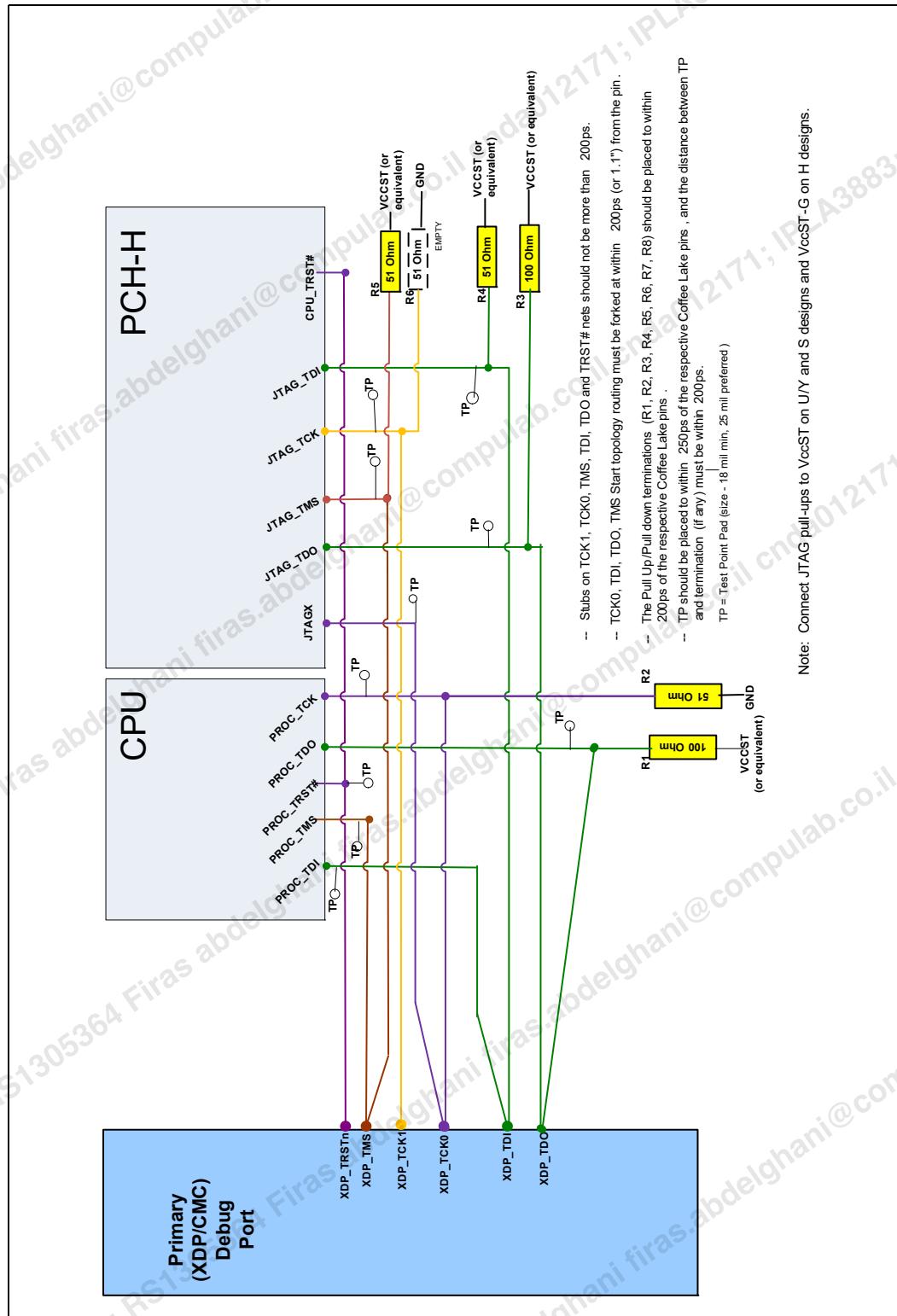


Figure 46-2. Primary Debug Port-JTAG Topology for Dual Scan Chain Only Design


**Table 46-3. Primary Debug Port - Dual Scan Chain Only Routing Guidelines (Sheet 1 of 3)**

Pin/Signal	Routing Rules
XDP_TCK0	<ul style="list-style-type: none"> •Route from XDP_TCK0 to Coffee Lake PROC_TCK and JTAGX as shown in Figure 46-6. <ul style="list-style-type: none"> — Make sure to fork the traces no more than 200ps (approx 1100 mil or 28mm) from XDP_TCK0 pin. • Test Point Placement <ul style="list-style-type: none"> — Must placed on secondary side — Place to within 250ps of Coffee Lake PROC_TCK pin and within 200ps of termination. — Pad size: Minimum 18mil, Preferred pad size 25 mil — Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>PROC_TCK Termination: $51 \Omega \pm 5\%$ pull down to GND</p> <ul style="list-style-type: none"> •Placed to within 200ps (approx 1100 min or 28mm) of Coffee Lake pins. <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <ul style="list-style-type: none"> •Any stub length on TCK trace can not be more than 200ps. The stub length should be minimized whenever possible. <p>Trace-to-Trace spacing: 3 x Trace Width</p> <p>Maximum Via count: 4</p> <p>Maximum Trace length: 1ns (roughly 6000 mil or 154 mm) [per segment, measure from XDP pin -> Coffee Lake pin]</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <ul style="list-style-type: none"> • Ideally, TCK should be routed directly to the socket pin of each processor and then exit the via array to continue on to the termination resistor on the trace. <p><i>Suggestion:</i> Provide a scope test point at Coffee Lake breakout via to verify signal integrity of the first platforms.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p> <p>Note: Note that some of the Intel reference designs might still have the JTAGX pull up. These pull up is only used to support Intel power-on, can be removed from the design.</p>
XDP_TCK1	<ul style="list-style-type: none"> •Route from XDP_TCK1 to Coffee Lake PCH_JTAG_TCK as shown in Figure 46-6. • Test Point Placement <ul style="list-style-type: none"> — Must placed on secondary side — Place to within 250ps of Coffee Lake pin and within 200ps of termination. — Pad size: Minimum 18mil, Preferred pad size 25 mil — Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>Termination: $51 \Omega \pm 5\%$ pull down to GND</p> <ul style="list-style-type: none"> •Placed to within 200ps (approx 1100 min or 28mm) of Coffee Lake pins. •Leave EMPTY. <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <ul style="list-style-type: none"> •Any stub length on TCK trace can not be more than 200ps. The stub length should be minimized whenever possible. <p>Trace-to-Trace spacing: 3 x Trace Width</p> <p>Maximum Via count: 4</p> <p>Maximum Trace length: 1ns (roughly 6000 mil or 154mm)</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <ul style="list-style-type: none"> • Ideally, TCK should be routed directly to the socket pin of each processor and then exit the via array to continue on to the termination resistor on the trace. <p><i>Suggestion:</i> Provide a scope test point at Coffee Lake breakout via to verify signal integrity of the first platforms.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>



Table 46-3. Primary Debug Port - Dual Scan Chain Only Routing Guidelines (Sheet 2 of 3)

Pin/Signal	Routing Rules
XDP_TMS	<ul style="list-style-type: none">• Route from XDP_TMS to Coffee Lake PROC_TMS and PCH_JTAG_TMS as shown in Figure 46-6.<ul style="list-style-type: none">— Make sure to fork the traces no more than 200ps (approx 1100 mil or 28mm) from XDP_TMS pin.• Test Point Placement<ul style="list-style-type: none">— Must placed on secondary side— Place to within 250ps of Coffee Lake pin and within 200ps of termination.— Pad size: Minimum 18mil, Preferred pad size 25 mil— Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>Termination: $51 \Omega \pm 5\%$ pull up to VCCSTG or equivalent</p> <p>• Placed to within 200ps (approx. 1100 min or 28mm) of Coffee Lake PCH_JTAG_TMS pin [note: PROC_TMS has on-die termination].</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <p>• Any stub length on this trace can not be more than 200ps. The stub length should be minimized whenever possible.</p> <p>Trace-to-Trace spacing: No limit, but at least 2x trace width when possible</p> <p>Maximum Via count: No limit, but should minimize whenever possible</p> <p>Maximum Trace length: 1ns (roughly 6000 mil or 154mm) [for each segment, measures from XDP->Coffee Lake pin]</p> <p>Length Matching: matching to +/- 270 mil (6.85mm) of TCK</p> <ul style="list-style-type: none">— Match PROC_TMS net to PROC_TCK net— Match PCH_JTAG_TMS to PCH_JTAG_TCK net— Length matching is recommended but it is optional [Note: Length matching to TCK might allow operating at higher TCK frequency] <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <ul style="list-style-type: none">• Ideally, TMS will be routed directly to the socket pin of each processor and then exit the via array to continue on to the termination resistor on the trace. <p><i>Suggestion:</i> Provide a scope test point at Coffee Lake breakout via to verify signal integrity of the first platforms.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>
XDP_TRSTn	<ul style="list-style-type: none">• Route daisy chain from XDP_TRSTn to Coffee Lake PROC_TRST# and PCH_TRST# as shown in Figure 46-6.• Test Point Placement<ul style="list-style-type: none">— Must placed on secondary side— Pad size: Minimum 18mil, Preferred pad size 25 mil— Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>Termination: None</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <p>Trace-to-Trace spacing: No limit. At least 1x trace width when possible</p> <p>Maximum Via count: No limit. Should minimize whenever possible</p> <p>Maximum Trace length: 2.5ns (roughly 15000 mil or 381mm)</p> <p>Length Matching: None</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p> <p>Note: Note that some of the Intel reference designs might still have the XDP_TRSTn pull down. These pull down is only used to support Intel power-on, can be removed from the design.</p>

**Table 46-3. Primary Debug Port - Dual Scan Chain Only Routing Guidelines (Sheet 3 of 3)**

Pin/Signal	Routing Rules
XDP_TDI	<ul style="list-style-type: none"> •Route from XDP_TDI to Coffee Lake PROC_TDI and PCH_JTAG_TDI as shown in Figure 46-6. <ul style="list-style-type: none"> — Make sure to fork the traces no more than 200ps (approx 1100 mil or 28mm) from XDP_TDI pin. • Test Point Placement <ul style="list-style-type: none"> — Must placed on secondary side — Place to within 250ps of Coffee Lake pin and within 200ps of termination. — Pad size: Minimum 18mil, Preferred pad size 25 mil — Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>Termination: $51 \Omega \pm 5\%$ pull up to VCCSTG or equivalent</p> <ul style="list-style-type: none"> •Placed to within 200ps (approx 1100 min or 28mm) of PCH_JTAG_TDI pin [Note: PROC_TDI has on-die termination]. <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <ul style="list-style-type: none"> •The stub length should be minimized whenever possible. <p>Trace-to-Trace spacing: No limit, At least 1x trace width when possible</p> <p>Maximum Via count: No limit, Should minimize whenever possible</p> <p>Maximum Trace length: 1ns (roughly 6000 mil or 154mm) [For each segment, measures from XDP->Coffee Lake pin]</p> <p>Length Matching: matching to +/- 270 mil (6.85mm) of TCK</p> <ul style="list-style-type: none"> — Match PROC_TDI net to PROC_TCK net — Match PCH_JTAG_TDI to PCH_JTAG_TCK net — Length matching is recommended but it is optional [Note: Length matching to TCK might allow operating at higher TCK frequency] <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>
XDP_TDO	<ul style="list-style-type: none"> •Route from XDP_TDO to Coffee Lake PROC_TDO and PCH_JTAG_TDO as shown in Figure 46-6. <ul style="list-style-type: none"> — Make sure to fork the traces no more than 200ps (approx 1100 mil or 28mm) from XDP_TDO pin. • Test Point Placement <ul style="list-style-type: none"> — Must placed on secondary side — Place to within 250ps of Coffee Lake pin and within 200ps of termination. — Pad size: Minimum 18mil, Preferred pad size 25 mil — Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>Termination: $100 \Omega \pm 5\%$ pull up to VCCSTG or equivalent</p> <ul style="list-style-type: none"> •Placed to within 200ps (approx 1100 min or 28mm) of each Coffee Lake pin. <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <ul style="list-style-type: none"> •Any stub length on this trace can not be more than 200ps. The stub length should be minimized whenever possible. <p>Trace-to-Trace spacing: No limit. At least 1x trace width when possible</p> <p>Maximum Via count: No limit. Should minimize whenever possible</p> <p>Maximum Trace length: 1ns (roughly 6000 mil or 154mm) [For each segment, measures from XDP->Coffee Lake pin]</p> <p>Length Matching: matching to +/- 270 mil (6.85mm) of TCK</p> <ul style="list-style-type: none"> — Match PROC_TDO net to PROC_TCK net — Match PCH_JTAG_TDO to PCH_JTAG_TCK net — Length matching is recommended but it is optional [Note: Length matching to TCK might allow operating at higher TCK frequency] <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>

46.1.1.2

Primary Debug Port: Observation Ports (CFG[0:19]) and PREQ#/PRDY# pins Routing Guidelines

Both XDP and CMC connector has defined 16 observation data signals (OBSDATA ports) and specialized signal ports (4 pairs OBS_FN for XDP or 2 pairs OBS_CLK for CMC).

Figure 46-3. Primary Debug Port: Observation Ports routing

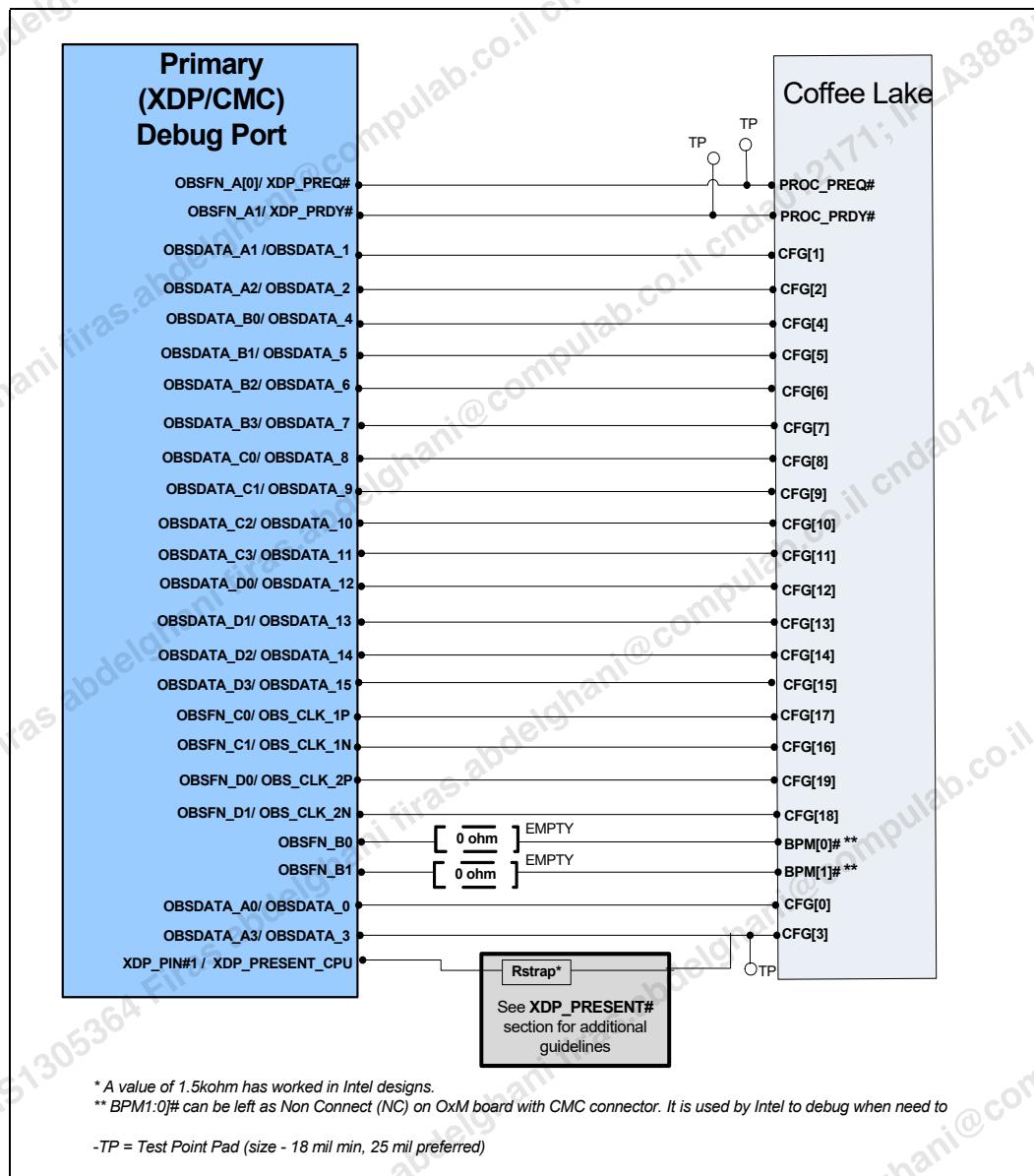
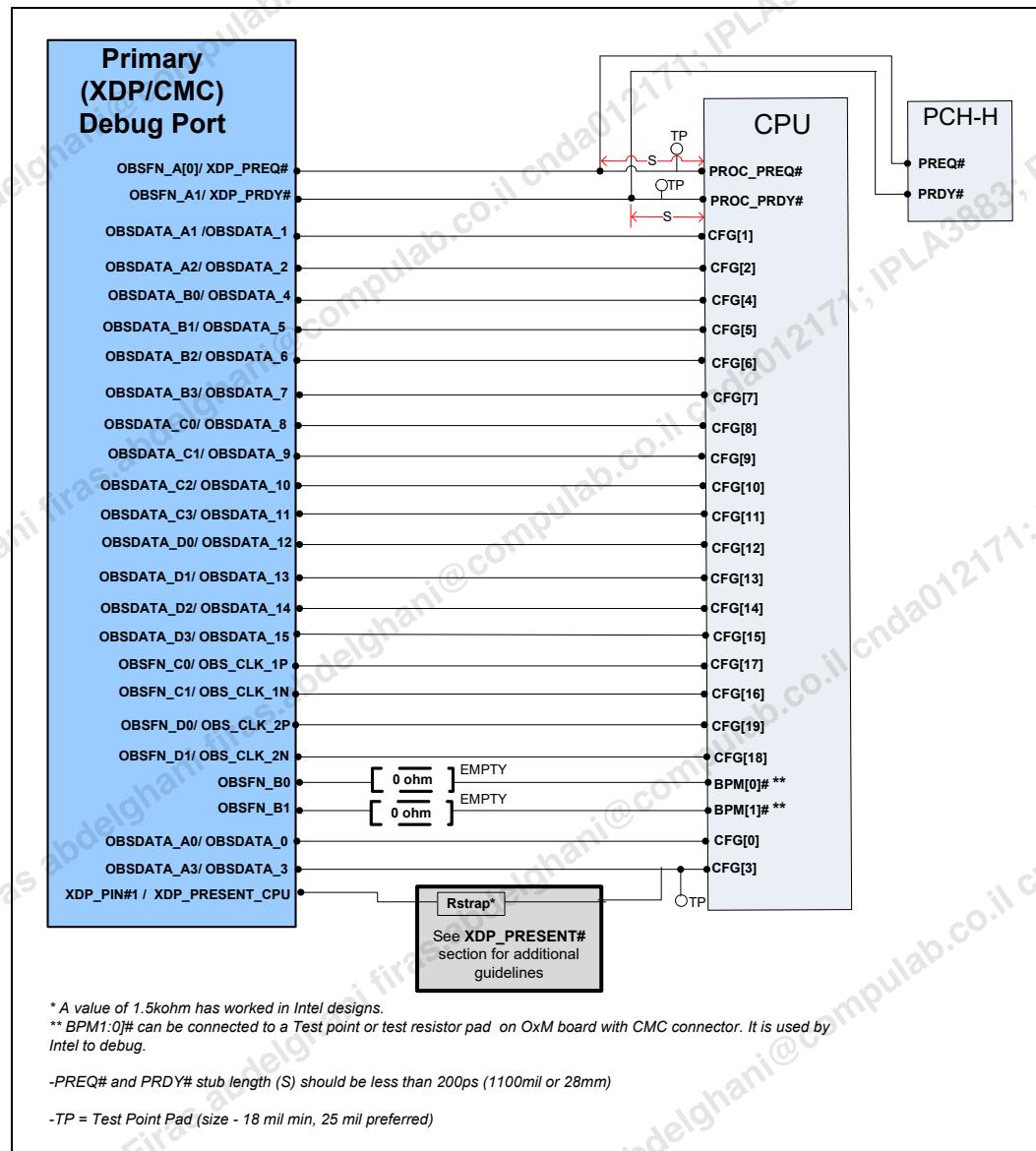


Figure 46-4. Primary Debug Port: Observation Ports Routing



**Table 46-4. Primary Debug Port - Observation Pins Routing Guidelines (Sheet 1 of 3)**

Pin/Signal	Routing Rules
XDP: OBSFN_A[0] OBSFN_A[1] CMC: XDP_PREQ# XDP_PRDY#	<ul style="list-style-type: none">• Route these signals to Coffee Lake Signals point-to-point according to Figure 46-8:<ul style="list-style-type: none">— Route XDP OBSFN_A[0] or CMC XDP_PREQ# to Coffee Lake PROC_PREQ#— Route XDP OBSFN_A[1] or CMC XDP_PRDY# to Coffee Lake PROC_PRDY#—• Test Point Placement<ul style="list-style-type: none">— Must placed on secondary side— Place to within 250ps of each Coffee Lake pin.— Pad size: Minimum 18mil, Preferred pad size 25 mil— Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>Termination: None</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm). The stub length should be minimized whenever possible.</p> <p>Trace-to-Trace spacing: No limit. At least 1xTrace Width when possible</p> <p>Maximum Via count: No limit. Should minimize whenever possible</p> <p>Maximum Trace length: 2ns (roughly 12000 mil or 308mm)</p> <p>Length Matching: None</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>

**Table 46-4. Primary Debug Port - Observation Pins Routing Guidelines (Sheet 2 of 3)**

Pin/Signal	Routing Rules
XDP: OBSDATA_A[2:0], OBSDATA_B[3:0] OBSDATA_C[3:0] OBSDATA_D[3:0] or CMC: OBSDATA_[15:0]	<ul style="list-style-type: none"> • Route these signals to Coffee Lake Signals point-to-point according to Figure 46-9: <p>XDP:</p> <ul style="list-style-type: none"> — Route OBSDATA_A[0] to Coffee Lake CFG[0]. — Route OBSDATA_A[1] to Coffee Lake CFG[1]. — Route OBSDATA_A[2] to Coffee Lake CFG[2]. — Route OBSDATA_A[3] to Coffee Lake CFG[3]. — Route OBSDATA_B[0] to Coffee Lake CFG[4]. — Route OBSDATA_B[1] to Coffee Lake CFG[5]. — Route OBSDATA_B[2] to Coffee Lake CFG[6]. — Route OBSDATA_B[3] to Coffee Lake CFG[7]. — Route OBSDATA_C[0] to Coffee Lake CFG[8]. — Route OBSDATA_C[1] to Coffee Lake CFG[9]. — Route OBSDATA_C[2] to Coffee Lake CFG[10]. — Route OBSDATA_C[3] to Coffee Lake CFG[11]. — Route OBSDATA_D[0] to Coffee Lake CFG[12]. — Route OBSDATA_D[1] to Coffee Lake CFG[13]. — Route OBSDATA_D[2] to Coffee Lake CFG[14]. — Route OBSDATA_D[3] to Coffee Lake CFG[15]. <p>CMC:</p> <ul style="list-style-type: none"> — Route pin1/OBSDATA_0 to Coffee Lake CFG[0]. — Route pin3/OBSDATA_1 to Coffee Lake CFG[1]. — Route pin5/OBSDATA_2 to Coffee Lake CFG[2]. — Route pin7/OBSDATA_3 to Coffee Lake CFG[3]. — Route pin9/OBSDATA_4 to Coffee Lake CFG[4]. — Route pin11/OBSDATA_5 to Coffee Lake CFG[5]. — Route pin13/OBSDATA_6 to Coffee Lake CFG[6]. — Route pin15/OBSDATA_7 to Coffee Lake CFG[7]. — Route pin2/OBSDATA_8 to Coffee Lake CFG[8]. — Route pin4/OBSDATA_9 to Coffee Lake CFG[9]. — Route pin6/OBSDATA_10 to Coffee Lake CFG[10]. — Route pin8/OBSDATA_11 to Coffee Lake CFG[11]. — Route pin10/OBSDATA_12 to Coffee Lake CFG[12]. — Route pin12/OBSDATA_13 to Coffee Lake CFG[13]. — Route pin14/OBSDATA_14 to Coffee Lake CFG[14]. — Route pin16/OBSDATA_15 to Coffee Lake CFG[15]. <ul style="list-style-type: none"> • Test Point Placement (CFG[3]) <ul style="list-style-type: none"> — Must placed on secondary side — Place to within 250ps of each Coffee Lake pin. — Pad size: Minimum 18mil, Preferred pad size 25 mil — Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>CFG[3] also needs to refer to Section 46.1.1.3.1 for additional routing guidelines.</p> <p>Termination: None</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm). The stub length should be minimized whenever possible.</p> <p>Trace-to-Trace spacing: No limit, but 2x trace width when possible</p> <p>Maximum Via count: No limit, but should minimize whenever possible</p> <p>Maximum Trace length: 2ns (roughly 12000 mil or 305mm) [For each segment, measures from XDP OBS pin ->Coffee Lake pin]</p> <p>Length Matching: within +/- 270 mil (6.85mm) of CFG[17]</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p> <p>Note: Note that some of the Intel reference designs might connect CFG[0] to HOOK[2]. This route is not needed on OXM board.</p>



Table 46-4. Primary Debug Port - Observation Pins Routing Guidelines (Sheet 3 of 3)

Pin/Signal	Routing Rules
XDP: OBSFN_C[0] OBSFN_C[1] OBSFN_D[0] OBSFN_D[1] CMC: OBS_CLK_1P OBS_CLK_1N OBS_CLK_2P OBS_CLK_2N	<ul style="list-style-type: none">Route these signals to Coffee Lake Signals point-to-point according to Figure 46-8:<ul style="list-style-type: none">Route XDP OBSFN_C0 or CMC OBS_CLK_1P to Coffee Lake CFG[17].Route XDP OBSFN_C1 or CMC OBS_CLK_1N to Coffee Lake CFG[16].Route XDP OBSFN_D0 or CMC OBS_CLK_2P to Coffee Lake CFG[19].Route XDP OBSFN_D1 or CMC OBS_CLK_2N to Coffee Lake CFG[18]. <p>Termination: None</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm). The stub length should be minimized whenever possible.</p> <p>Trace-to-Trace spacing: 3 x Trace Width</p> <p>Maximum Via count: 4</p> <p>Maximum Trace length: 2ns (roughly 12000 mil or 305mm)</p> <p>Length Matching: within +/- 270 mil (6.85mm) of CFG[17]</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>
XDP Only: OBSFN_B[1:0]	<ul style="list-style-type: none">Route these signals to Coffee Lake Signals according to Figure 46-8:<ul style="list-style-type: none">Route OBSFN_B0 to Coffee Lake BPM#[0].Route OBSFN_B1 to Coffee Lake BPM#[1]. <p>Termination: None</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <p>• Any stub length on this trace can not be more than 200ps. The stub length should be minimized whenever possible.</p> <p>Trace-to-Trace spacing: No limit, but at least 1x trace width when possible</p> <p>Maximum Via count: No limit, but should minimize whenever possible</p> <p>Maximum Trace length: 2ns (roughly 12000 mil or 305mm)</p> <p>Length Matching: within +/- 270 mil (6.85mm) of each other</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>
XDP Coffee Lake BPM#[3:2]# CMC: Coffee Lake BPM#[3:0]	<ul style="list-style-type: none">Routed as test points or resistor pads on the platform. <p>Note: The test points or pads must be placed in a location that is probe accessible (avoid location that is blocked by thermal solutions) so that Intel would be able to access them when debug by Intel is required.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>

46.1.1.3 Primary Debug Port HOOKs, SMBus, XDP_PRESENT_N, VCC_OBS and Ground Signals Routing Guidelines

This section describes Primary Debug port's HOOK/system control signals routing guidelines. Unless otherwise indicated, routing guidelines in this section apply to both primary XDP and primary CMC connectors.

Figure 46-5. Primary Debug Port-HOOK, VCC_OBS signals Route Map

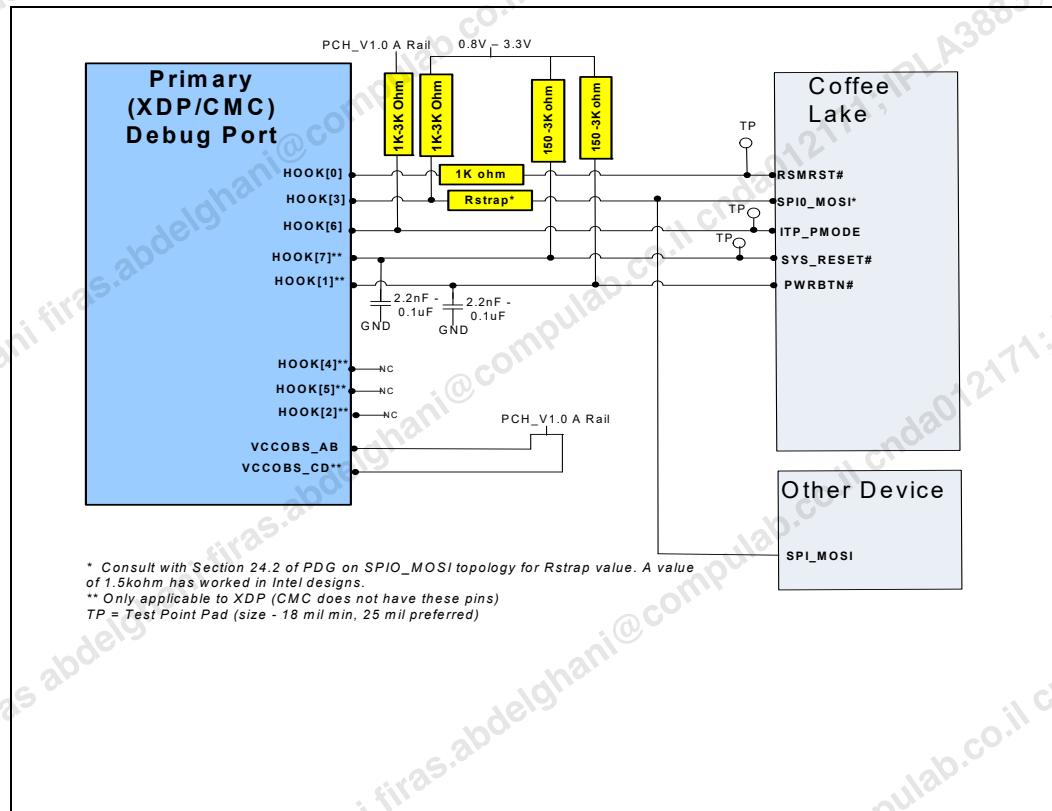
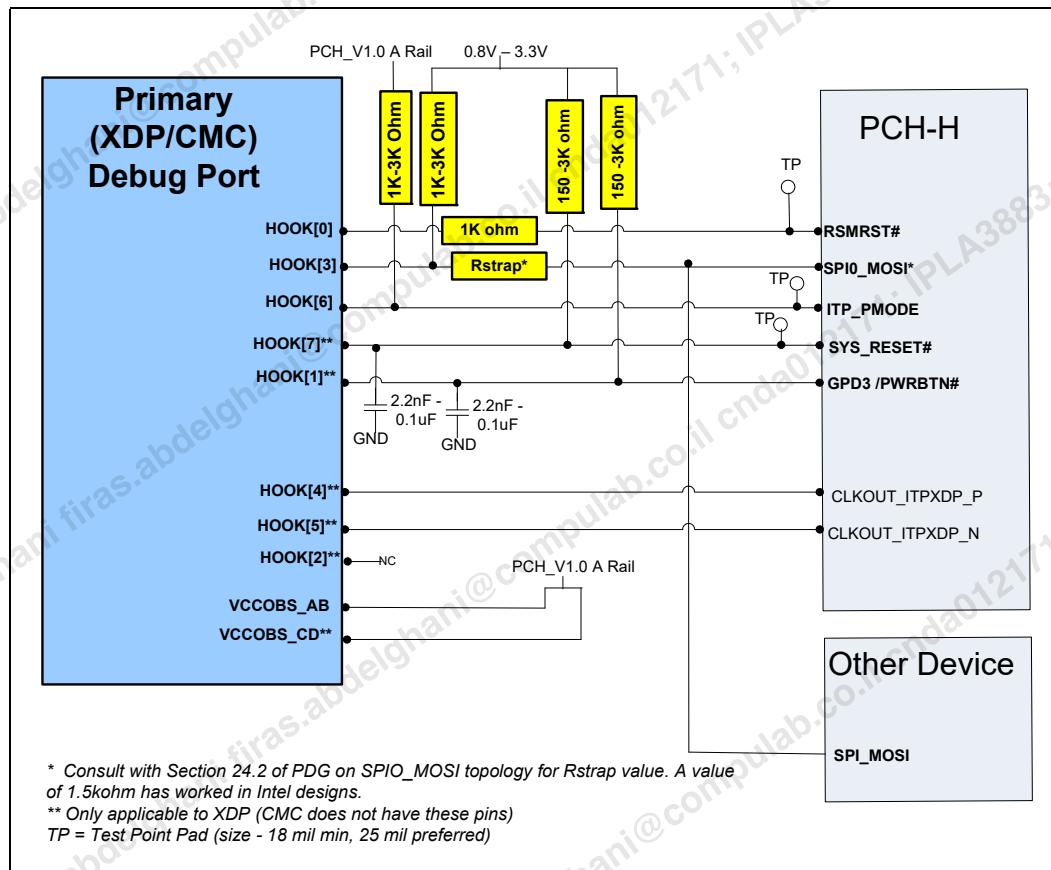


Figure 46-6. Primary Debug Port-HOOK, VCC_OBS signals Route Map




**Table 46-5. Primary Debug Port - HOOK, VCC_OBS, SCL/SDA, Ground signals Routing
(Sheet 1 of 4)**

Pin/Signal	Routing Rules	Notes
XDP Ground pins#2, 7, 8, 13, 14, 19, 20, 25, 26, 31, 32, 37, 38, 49, 50, 59 CMC: Pin#19	<ul style="list-style-type: none"> Connect all of the XDP connector GND pins (except of XDP pin#1) directly to a GND plane through individual vias. Keep trace lengths on these connections to a minimum. Refer Section 46.1.1.3.1 for XDP pin# 1 routing Guidelines 	
XDP: VCC_OBS_AB VCC_OBS_CD CMC: VccOBS_AB	<ul style="list-style-type: none"> Connect VCC_OBS_AB/ VccOBS_AB and VCC_OBS_CD to the PCH_1.0V A Rail or equivalent Minimum Trace Width: 10 mil (0.254mm) <p>Note: The ITP probe will have an internal 220uF capacitor on each VCC_OBS rail. It is required to take this into account in the design of the Power Delivery Network in order to minimize voltage droops when hot-plugging the ITP. These droops are caused mainly by the in-rush currents needed to charge the two 220uF capacitors</p>	
XDP/CMC: HOOK[0]	<ul style="list-style-type: none"> Route these signals to Coffee Lake Signals according to Figure 46-9: <ul style="list-style-type: none"> Route HOOK[0] to Coffee Lake RSMRST#. Places a 1K Ω 5% series resistor on the trace between processor XDP HOOK[0] and RSMRST# trace Consult RSMRST# topology and guidelines sections in this Platform Design Guide (PDG) for termination information and additional routing guidelines. <p>Termination: Consult RSMRST# topology and guidelines sections in this Platform Design Guide (PDG) for termination information and additional RSMRST# routing guidelines.</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <p>Trace-to-Trace spacing: No limit for XDP. Consult RSMRST# routing guidelines for additional routing requirement.</p> <p>Maximum Via count: No limit for XDP. Consult RSMRST# routing guidelines for additional routing requirement.</p> <p>Maximum Trace length: 2.5ns (roughly 15000 mil or 381mm) [from XDP to Coffee Lake RSMRST# pin]</p> <p>Length Matching: None</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>	

**Table 46-5. Primary Debug Port - HOOK, VCC_OBS, SCL/SDA, Ground signals Routing
(Sheet 2 of 4)**

Pin/Signal	Routing Rules	Notes
XDP/CMC: HOOK[3]	<ul style="list-style-type: none">Route these signals to Coffee Lake Signals according to Figure 46-9:<ul style="list-style-type: none">Route HOOK[3] to the strapping resistor (Rstrap) connecting to Coffee Lake SPIO_MOSI pin and other device (if any) SPIO_MOSI.Rstrap need to be place to within 200ps (1100 mil or 28mm) of the T-point connection to main SPIO_MOSI trace.Resistor RStrap value is platform dependent. A value of 1.5kΩ has worked in Intel designs. Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for the SPIO_MOSI Rstrap value and additional routing guidelines. Termination: Resistor can be value from 1K to 3K Ω pull up to voltage value from 0.8V-3.3V.<ul style="list-style-type: none">Place termination between XDP/CMC and Rstrap. it should be within 200ps of debug port HOOK[3] pin.Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for the SPIO_MOSI termination value and additional routing guidelines. Stub length: 200ps (approx. 1100 mil or 28mm)<ul style="list-style-type: none">Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_MOSI routing guidelines. Trace-to-Trace spacing: No limit for XDP. Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_MOSI routing guidelines. Maximum Via count: No limit for XDP. Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_MOSI routing guidelines. Maximum Trace length: Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_MOSI routing guidelines. Length Matching: Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for the SPIO_MOSI termination value and additional routing guidelines Refer to Section 46.1.6 for additional debug port PCB layout rules. Refer to Section 46.1.8 for debug port depopulation rule.	
HOOK[6]	<ul style="list-style-type: none">Route these signals to Coffee Lake Signals according to Figure 46-9:<ul style="list-style-type: none">Route HOOK[6] to Coffee Lake ITP_PMODE. Termination: Resistor value from 1K Ω to 3K Ω pull up to PCH_V1.0A Rail.<ul style="list-style-type: none">Place termination to within 200ps (approx 1100 or 28mm) of XDP/CMC HOOK[6] pin. Stub length: 200ps (approx. 1100 mil or 28mm)<ul style="list-style-type: none">Any stub length on this trace can not be more than 200ps. The stub length should be minimized whenever possible. Trace-to-Trace spacing: No limit. Maximum Via count: No limit, should be minimize whenever possible. Maximum Trace length: 2ns (roughly 12000 mil or 305mm) [from XDP to Coffee Lake pin] Length Matching: None Refer to Section 46.1.6 for additional debug port PCB layout rules. Refer to Section 46.1.8 for debug port depopulation rule.	



**Table 46-5. Primary Debug Port - HOOK, VCC_OBS, SCL/SDA, Ground signals Routing
(Sheet 3 of 4)**

Pin/Signal	Routing Rules	Notes
XDP: HOOK[1]	<ul style="list-style-type: none"> • Route these signals to Coffee Lake Signals according to Figure 46-9: <ul style="list-style-type: none"> — Route HOOK[1] to Coffee Lake PWRBTN# or board Reset Logic controlling the system power button. — Provide a pull up (resistor range from 150 to 3K Ω and pull up voltage range from 0.8V to 3.3V can be driven by ITP) on this connection <ul style="list-style-type: none"> - Note that only one pull up is needed when there are multiple XDP HOOK[1] connections. — Place a capacitor (value can be range from 2.2nF to 0.1uF) pull down to ground to within 200ps (approx 1100 or 28mm) of XDP HOOK[1] pin. <p>Termination: consult PWRBTN# routing guidelines for exact termination values and additional routing requirement.</p> <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <p>Trace-to-Trace spacing: No limit for XDP. Consult PWRBTN# routing guidelines for additional routing requirement.</p> <p>Maximum Via count: No limit for XDP. Consult PWRBTN# routing guidelines for additional routing requirement.</p> <p>Maximum Trace length: 2.7ns (roughly 16100 mil or 409mm)</p> <p>Length Matching: None</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>	
XDP: HOOK[2]	<ul style="list-style-type: none"> • This XDP pin should be left as No Connect (NC) <p>Note: Some Intel Reference Design might connect HOOK[2] to CFG[0]. HOOK[2] routing is only required for Intel debug, its routing is OPTIONAL.</p>	
XDP only: HOOK[4], HOOK[5]	<ul style="list-style-type: none"> • Route these signals to Coffee Lake Signals according to Figure 46-9: <ul style="list-style-type: none"> — Route HOOK[4] point-to-point to Coffee Lake CLKOUT_ITPXDP_P. — Route HOOK[5] point-to-point to Coffee Lake CLKOUT_ITPXDP_N. <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <p>Trace-to-Trace spacing: No limit. At least 1 x Trace Width when possible.</p> <p>Maximum Via count: No limit. Should be minimize whenever possible.</p> <p>Maximum Trace length: 2.5ns (roughly 15000 mil or 381mm)</p> <p>Length Matching: within +/- 10 mil (0.25mm) of each other</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p> <p>Note: Route of HOOK[4] and HOOK[5] is Optional. They can be left No Connect (NC) on a OxM board.</p>	

**Table 46-5. Primary Debug Port - HOOK, VCC_OBS, SCL/SDA, Ground signals Routing
(Sheet 4 of 4)**

Pin/Signal	Routing Rules	Notes
XDP: HOOK[7]	<ul style="list-style-type: none">• Route these signals to Coffee Lake Signals according to Figure 46-9:<ul style="list-style-type: none">— Route HOOK[7] to Coffee Lake SYS_RESET# or board Reset Logic capable of initiating a warm Reset cycle.— Provide a pull up (resistor range from 150 to 3K Ω and pull up voltage range from 0.8V to 3.3V can be driven by ITP) on this connection<ul style="list-style-type: none">- Note that only one pull up is needed when there are multiple XDP HOOK[7] connections.— Place a capacitor (value can be range from 2.2nF to 0.1uF) pull down to ground to within 200ps (approx 1100 or 28mm) of XDP HOOK[7] pin.Termination: Consult Section 30.2.1, "SYS_RESET# Usage Model" for termination values and additional routing requirement.Stub length: 200ps (approx. 1100 mil or 28mm). The stub length should be minimized whenever possible.Trace-to-Trace spacing: No limit for XDP. Consult SYS_RESET# routing guidelines for additional routing requirement.Maximum Via count: No limit for XDP. Consult SYS_RESET# routing guidelines for additional routing requirement.Maximum Trace length: 2.7ns (roughly 16100 mil or 409mm)Length Matching: NoneRefer to Section 46.1.6 for additional debug port PCB layout rules.Refer to Section 46.1.8 for debug port depopulation rule.	
XDP: SCL/SDA	<ul style="list-style-type: none">• I²C*/SMBus is Optional connection for XDP.• If connected:<ul style="list-style-type: none">— Route the debug-port SDA pin to the SDA signal of the SMBus on the system.— Route the debug port SCL pin to the SCL signal of the SMBus on the system.— provide the pull ups and follow the routing guidelines according to Section 33.3.5, "SMBus and I²C Topology Guidelines" in this guide.	

46.1.1.3.1 Primary Debug Port XDP_PRESENT# Routing Guidelines

This section describes XDP_PRESENT# connectivity of primary debug port.

Figure 46-7. Primary Debug Port-XDP_PRESENT# Connectivity

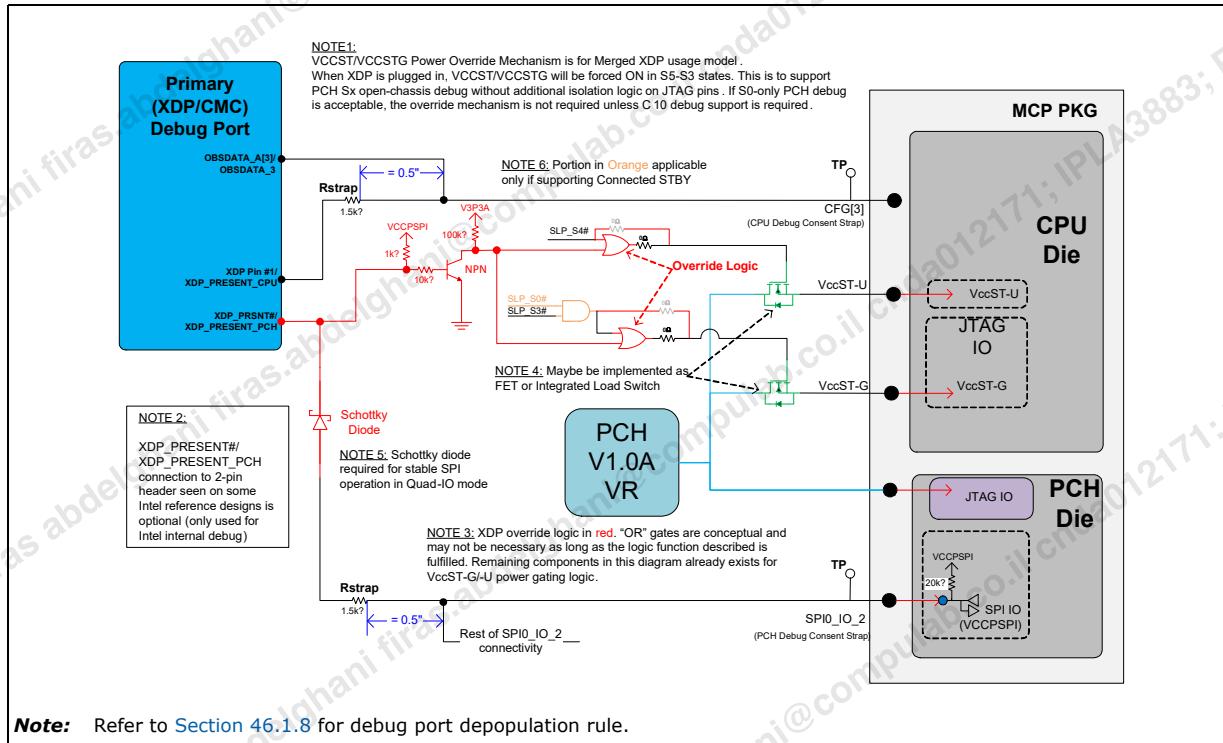
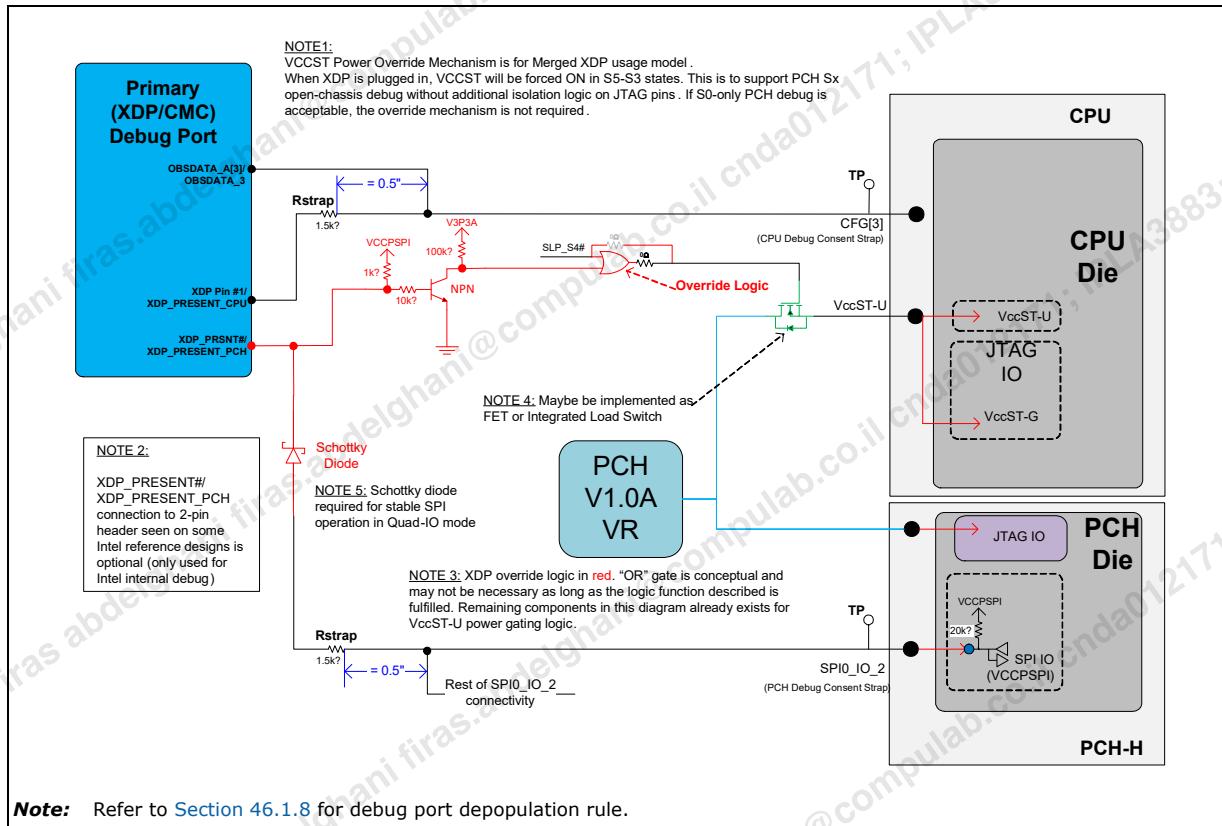


Figure 46-8. Primary Debug Port-XDP_PRESENT# Connectivity

Table 46-6. Primary Debug Port - XDP_PRESENT Routing Guidelines (Sheet 1 of 2)

Signal (pin#)	Routing Rules	Notes
XDP: XDP_pin# 1 (pin# 1) CMC: XDP_PRESENT_CPU (pin# 23)	<ul style="list-style-type: none"> Route these signals to Coffee Lake pin according to Figure 46-11: <ul style="list-style-type: none"> Route XDP pin# 1 or CMC XDP_PRESENT_CPU pin to Coffee Lake CFG[3] Places Rstrap resistor on the trace between debug port pin and CFG[3]. Rstrap should be placed to within 100ps (500 mil or 12.5 mm) of the T-point connection to main CFG[3] trace. Check Section 49.3.27, "Processor Strapping" for CFG[3] Rstrap value. NOTE: Consult Section 46.1.1.2, "Primary Debug Port: Observation Ports (CFG[0:19]) and PREQ#/PRDY# pins Routing Guidelines" for additional CFG[3] routing guidelines. <p>Stub length: 200ps (approx. 1100 mil or 28mm)</p> <p>Trace-to-Trace spacing: No limit for XDP_PRESENT signals.</p> <p>Maximum Via count: No limit for XDP. Should be minimized whenever possible.</p> <p>Maximum Trace length: 2ns (roughly 12000 mil or 305mm) [measure from debug Port pin#1 to CFG[3]].</p> <p>Length Matching: None for XDP_PRESENT_CPU or XDP pin#1. Refer Section 46.1.1.2 for CFG[3] length matching rule.</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>	

**Table 46-6. Primary Debug Port - XDP_PRESENT Routing Guidelines (Sheet 2 of 2)**

Signal (pin#)	Routing Rules	Notes
XDP: XDP_PRESENT# (pin# 60) CMC: XDP_PRESENT_PCH (pin#24)	<ul style="list-style-type: none"> Route these signals to Coffee Lake Signals according to Figure 46-11: <ul style="list-style-type: none"> Route XDP XDP_PRESENT# or CMC XDP_PRESENT_PCH pin to Coffee Lake SPIO_IO2 pin. Rstrap should be placed to within 100ps (500 mil or 12.5 mm) of the T-point connection to main SPIO_IO2 trace. Consult section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for the SPIO_IO2 Rstrap value and additional SPIO_IO2 routing guidelines. Test Point Placement (SPIO_IO2) <ul style="list-style-type: none"> Must be placed on secondary side Place to within 250ps of Coffee Lake pin. Pad size: Minimum 18mil, Preferred pad size 25 mil Refer section Section 46.1.7 for additional routing requirement to support Intel® Silicon View Technology DFM HVM solution <p>Stub length: 200ps (approx. 1100 mil or 28mm). Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_IO2 routing guidelines.</p> <p>Trace-to-Trace spacing: No limit for debug port. Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_IO2 routing guidelines</p> <p>Maximum Via count: No limit for debug port. Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_IO2 routing guidelines</p> <p>Maximum Trace length: Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_IO2 routing guidelines</p> <p>Length Matching: Consult Section 24.2, "Serial Peripheral Interface (SPI) Topology Guidelines" for additional SPIO_IO2 routing guidelines.</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p> <p>Refer to Section 46.1.8 for debug port depopulation rule.</p>	

46.1.1.4 Primary XDP Connector Pin Out

Table 46-7 documents the pinout of Primary XDP connector.

Table 46-7. Primary XDP Connector Pinout (Sheet 1 of 2)

Pin	XDP Signal Name	Target Signal	I/O	Device	Pin	XDP Signal Name	Target Signal	I/O	Device
1	XDP Pin#1 ²	Refer XDP_PRESENT# routing guidelines	NA	Coffee Lake	2	GND	GND	NA	
3	OBSFN_A0	PROC_PREQ#	O	Coffee Lake	4	OBSFN_C0	CFG(17)	I	Coffee Lake
5	OBSFN_A1	PROC_PRDY#	I	Coffee Lake	6	OBSFN_C1	CFG(16)	I	Coffee Lake
7	GND	GND	NA		8	GND	GND	NA	
9	OBSDATA_A0	CFG[0]	I/O	Coffee Lake	10	OBSDATA_C0	CFG[8]	I/O	Coffee Lake
11	OBSDATA_A1	CFG[1]	I/O	Coffee Lake	12	OBSDATA_C1	CFG[9]	I/O	Coffee Lake
13	GND	GND	NA		14	GND	GND	NA	
15	OBSDATA_A2	CFG[2]	I/O	Coffee Lake	16	OBSDATA_C2	CFG[10]	I/O	Coffee Lake
17	OBSDATA_A3	CFG[3]	I/O	Coffee Lake	18	OBSDATA_C3	CFG[11]	I/O	Coffee Lake
19	GND	GND	NA		20	GND	GND	NA	
21	OBSFN_B0	BPM#[0]	I/O	Coffee Lake	22	OBSFN_D0	CFG(19)	I	Coffee Lake



Table 46-7. Primary XDP Connector Pinout (Sheet 2 of 2)

Pin	XDP Signal Name	Target Signal	I/O	Device	Pin	XDP Signal Name	Target Signal	I/O	Device
23	OBSFN_B1	BPM#[1]	I/O	Coffee Lake	24	OBSFN_D1	CFG(18)	I	Coffee Lake
25	GND	GND	NA		26	GND	GND	NA	
27	OBSDATA_B0	CFG[4]	I/O	Coffee Lake	28	OBSDATA_D0	CFG[12]	I/O	Coffee Lake
29	OBSDATA_B1	CFG[5]	I/O	Coffee Lake	30	OBSDATA_D1	CFG[13]	I/O	Coffee Lake
31	GND	GND	NA		32	GND	GND	NA	
33	OBSDATA_B2	CFG[6]	I/O	Coffee Lake	34	OBSDATA_D2	CFG[14]	I/O	Coffee Lake
35	OBSDATA_B3	CFG[7]	I/O	Coffee Lake	36	OBSDATA_D3	CFG[15]	I/O	Coffee Lake
37	GND	GND	NA		38	GND	GND	NA	
39	HOOK0	RSMRST#	I	Coffee Lake	40	ITPCLK/HOOK4 ¹	CLKOUT_ITPX_DP_P	I	Coffee Lake
41	HOOK1	PWRBTN#	O	Coffee Lake	42	ITPCLK#/HOOK5	CLKOUT_ITPX_DP_N	I	Coffee Lake
43	VCC_OBS_AB	PCH V1.0A	NA		44	VCC_OBS_CD	PCH V1.0A	NA	
45	HOOK2 ³	Open	NA		46	HOOK6/RESET#	ITP_PMODE	I	Coffee Lake
47	HOOK3 ¹	SPIO_MOSI	O	Coffee Lake	48	HOOK7/DBR#	SYS_RESET#	O	Coffee Lake
49	GND	GND	NA		50	GND	GND	NA	
51	XDP_SDA ¹	SDA	I/O	system	52	XDP_TDO	PROC_TDO / PCH_JTAG_TD_O	I	Coffee Lake
53	XDP_SCL ¹	SCL	I/O	system	54	XDP_TRSTn	PROC_TRST#/ PCH_TRST#	O	Coffee Lake
55	XDP_TCK1	PCH_JTAG_TCK	O	Coffee Lake	56	XDP_TDI	PROC_TDI / PCH_JTAG_TDI	O	Coffee Lake
57	XDP_TCK0	PROC_TCK / JTAGX	O	Coffee Lake	58	XDP_TMS	PROC_TMS / PCH_JTAG_TMS	O	Coffee Lake
59	GND	GND	NA		60	GND ² (XDP_PRESENT#)	Refer XDP_PRESENT# routing guidelines	NA	system

Notes:

1. These signals are optional, can be left as OPEN/No-Connect.
2. Refer XDP_PRESENT# section for additional routing guidelines.
3. Routing of this signal to CFG[0] is OPTIONAL.



46.1.1.5 Primary CMC Pin Out

Table 46-8 documents the pinout of Primary CMC connector.

Table 46-8. Primary CMC Connector Pinout

Pin	CMC Signal Name	Target Signal	I/O	Device	Pin	CMC Signal Name	Target Signal	I/O	Device
1	OBSDATA_0	CFG[0]	I/O	Coffee Lake	2	OBSDATA_8	CFG[8]	I/O	Coffee Lake
3	OBSDATA_1	CFG[1]	I/O	Coffee Lake	4	OBSDATA_9	CFG[9]	I/O	Coffee Lake
5	OBSDATA_2	CFG[2]	I/O	Coffee Lake	6	OBSDATA_10	CFG[10]	I/O	Coffee Lake
7	OBSDATA_3	CFG[3]	I/O	Coffee Lake	8	OBSDATA_11	CFG[11]	I/O	Coffee Lake
9	OBSDATA_4	CFG[4]	I/O	Coffee Lake	10	OBSDATA_12	CFG[12]	I/O	Coffee Lake
11	OBSDATA_5	CFG[5]	I/O	Coffee Lake	12	OBSDATA_13	CFG[13]	I/O	Coffee Lake
13	OBSDATA_6	CFG[6]	I/O	Coffee Lake	14	OBSDATA_14	CFG[14]	I/O	Coffee Lake
15	OBSDATA_7	CFG[7]	I/O	Coffee Lake	16	OBSDATA_15	CFG[15]	I/O	Coffee Lake
17	OBS_CLK_1P	CFG[17]	I	Coffee Lake	18	OBS_CLK_2P	CFG[19]	I	Coffee Lake
19	GND	GND	NA		20	OBS_CLK_2N	CFG[18]	I	Coffee Lake
21	OBS_CLK_1N	CFG[16]	I	Coffee Lake	22	VCCOBS_AB	PCH V1.0 A	NA	
23	XDP_PRESENT_C PU#	Refer XDP_PRESENT# section	NA	system	24	XDP_PRESENT_P CH#	Refer XDP_PRESENT # section	NA	System
25	HOOK[3]	SPI_MOSI	O	Coffee Lake	26	HOOK[6]	ITP_PMODE	I	Coffee Lake
27	HOOK[0]	RSMRST#	I	Coffee Lake	28	XDP_TRSTn	PROC_TRST# / PCH_TRST#	O	Coffee Lake
29	XDP_TDI	PROC_TDI / PCH_JTAG_TDI	O	Coffee Lake	30	XDP_TMS	PROC_TMS / PCH_JTAG_TMS	O	Coffee Lake
31	XDP_TCK1	PCH_JTAG_TC K	O	Coffee Lake	32	XDP_TCK0	PROC_TCK / JTAGX	O	Coffee Lake
33	XDP_PREQ#	PROC_PREQ#	O	Coffee Lake	34	XDP_PRDY#	PROC_PRDY#	I	Coffee Lake
35	XDP_TDO	PROC_TDO / PCH_JTAG_TD O	I	Coffee Lake					

46.1.2 Secondary Debug Port Routing Guidelines

Unless otherwise indicated, routing guidelines in this section apply to both secondary XDP and secondary CMC connectors.

JTAG pins, HOOK pins, XDP_PRESENT#, VCCOBS pins, SCL/SDA pins of this secondary debug port can be left as No connect (NC) unless indicated otherwise.



46.1.2.1

Secondary Debug Port Observation Ports Routing Guidelines

The XDP connector has defined four separate observation ports (OBS ports) named A through D. Each port contains four data signals (OBS_DATA), and two specialized signals (OBS_FN). Likewise, CMC has defined 16 OBS data pins (OBSDATA) and 2 set of OBS Clock pins (OBS_CLK_[1:2]P/N).

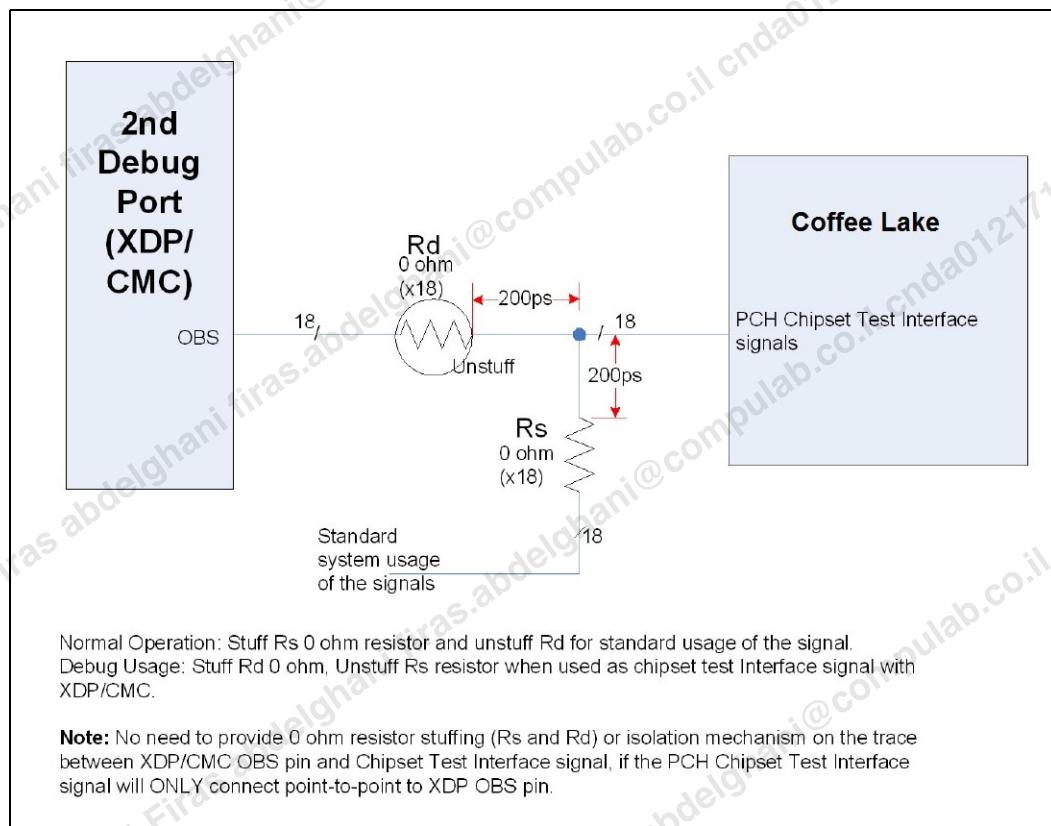
The Coffee Lake Chipset Test Interface signals are used by Intel when debugging customer platforms. There are 18 PCH Chipset Test Interface signals; Those signals need to be routed to secondary XDP or CMC OBS pins according to [Figure 46-9](#) and [Table 46-9](#).

**Table 46-9. Secondary Debug Port- OBS Pins Routing Requirements (Sheet 1 of 2)**

Pin/Signal	Routing Rules	Notes
XDP pins: OBSDATA_A[3:0], OBSDATA_B[3:0], OBSFN_C[1:0], OBSDATA_C[3:0], OBSDATA_D[3:0] CMC: pins OBSDATA_[0:18] OBS_CLK_1P OBS_CLK_2P	<p>XDP:</p> <ul style="list-style-type: none"> •Route these OBS pins to Coffee Lake according to Figure 46-4: <p>XDP:</p> <ul style="list-style-type: none"> — Route OBSDATA_A[0] to PCH GPP_E1 / SATAXPCIE1 / SATAGP1 — Route OBSDATA_A[1] to PCH GPP_E2 / SATAXPCIE2 / SATAGP2 — Route OBSDATA_A[2] to PCH GPP_E3 / CPU_GPO — Route OBSDATA_A[3] to PCH GPP_E4 / DEVSLP0 — Route OBSDATA_B[0] to PCH GPP_E5 / DEVSLP1 — Route OBSDATA_B[1] to PCH GPP_E6 / DEVSLP2 — Route OBSDATA_B[2] to PCH GPP_E7 / CPU_GP1 — Route OBSDATA_B[3] to PCH GPP_E8 / SATALED# — Route OBSFN_C[0] to PCH GPP_E0 / SATAXPCIE0 / SATAGP0 — Route OBSFN_C[1] to PCH GPP_F4 / SATAXPCIE7 / SATAGP7 — Route OBSDATA_C[0] to PCH GPP_E9 / USB2_OC0# — Route OBSDATA_C[1] to PCH GPP_E10 / USB2_OC1# — Route OBSDATA_C[2] to PCH GPP_E11 / USB2_OC2# — Route OBSDATA_C[3] to PCH GPP_E12 / USB2_OC3# — Route OBSDATA_D[0] to PCH GPP_F0 / SATAXPCIE3 / SATAGP3 — Route OBSDATA_D[1] to PCH GPP_F1 / SATAXPCIE4 / SATAGP4 — Route OBSDATA_D[2] to PCH GPP_F2 / SATAXPCIE5 / SATAGP5 — Route OBSDATA_D[3] to PCH GPP_F3 / SATAXPCIE6 / SATAGP6 <p>CMC:</p> <ul style="list-style-type: none"> — Route pin1/OBSDATA_0 to PCH GPP_E1 / SATAXPCIE1 / SATAGP1. — Route pin3/OBSDATA_1 to PCH GPP_E2 / SATAXPCIE2 / SATAGP2 — Route pin5/OBSDATA_2 to PCH GPP_E3 / CPU_GPO — Route pin7/OBSDATA_3 to PCH GPP_E4 / DEVSLP0 — Route pin9/OBSDATA_4 to PCH GPP_E5 / DEVSLP1 — Route pin11/OBSDATA_5 to PCH GPP_E6 / DEVSLP2 — Route pin13/OBSDATA_6 to PCH GPP_E7 / CPU_GP1 — Route pin15/OBSDATA_7 to PCH GPP_E8 / SATALED# — Route pin17/OBS_CLK_1P to PCH GPP_E0 / SATAXPCIE0 / SATAGP0 — Route pin2/OBSDATA_8 to PCH GPP_E9 / USB2_OC0# — Route pin4/OBSDATA_9 to PCH GPP_E10 / USB2_OC1# — Route pin6/OBSDATA_10 to PCH GPP_E11 / USB2_OC2# — Route pin8/OBSDATA_11 to PCH GPP_E12 / USB2_OC3# — Route pin10/OBSDATA_12 to PCH GPP_F0 / SATAXPCIE3 / SATAGP3 — Route pin12/OBSDATA_13 to PCH GPP_F1 / SATAXPCIE4 / SATAGP4 — Route pin14/OBSDATA_14 to PCH GPP_F2 / SATAXPCIE5 / SATAGP5 — Route pin16/OBSDATA_15 to PCH GPP_F3 / SATAXPCIE6 / SATAGP6 — Route pin18/OBS_CLK_2P to PCH GPP_F4 / SATAXPCIE7 / SATAGP7 <p>Stub length: 200ps (approx. 1100mil or 28mm). The stub length should be minimized whenever possible.</p> <p>Maximum Via count: 4 for OBS_C[1:0]/OBS_CLK_[2,1]P signals, No limit of others.</p> <p>Length Matching: ±50ps (roughly 270mil or 6.85mm)</p> <ul style="list-style-type: none"> •These group of signal must be length matched to ±50ps of flight time with respect to OBSFN_C[1] for XDP or OBSCLK_2P for CMC. <p>Trace-To-Trace Spacing:</p> <ul style="list-style-type: none"> •XDP: OBSFN_C[0:1]: 3 x Trace Width •CMC: OBS_CLK_1P and OBS_CLK_2P: 3xTrace Width •Others OBS signals have no trace spacing restriction. It is recommended; however, to keep at least 2xTrace Width when possible. <p>Maximum Trace length: 2ns (roughly 12000mil or 305mm)</p> <p>Refer to Section 46.1.6 for additional debug port PCB layout rules.</p>	

Table 46-9. Secondary Debug Port- OBS Pins Routing Requirements (Sheet 2 of 2)

Pin/Signal	Routing Rules	Notes
XDP pins: OBSFN_A[1:0] OBSFN_D[1:0] OBSFN_B[1:0]	Leave these secondary debug port OBS pins as NO CONNECT (NC)	
CMC: pins OBS_CLK_1N, OBS_CLK_2N		

Figure 46-9. Secondary Debug Port - PCH Chipset Test Interfaces


46.1.2.2 Secondary XDP HOOK0 Routing Guidelines

This routing guidelines apply only to Secondary XDP. For Secondary CMC, HOOK0 can be left as No Connect (NC).

Route XDP HOOK[0] to Coffee Lake RSMRST# pin as shown in Figure 46-9.

Follow the HOOK[0] routing rules in Table 46-5.



46.1.2.3 Secondary XDP VCCOBS_AB and VCCOBS_CD Routing Guidelines

This routing guidelines apply only to Secondary XDP. For Secondary CMC, VCCOBS_AB can be left as No Connect (NC).

Route point to point from XDP VCCOBS_AB and VCCOBS_CD to PCH_V1.0A rail or equivalent as shown in [Figure 46-9](#).

Follow the routing rules of VCC_OBS_AB and VCC_OBS_CD in [Table 46-5](#).

46.1.2.4 Secondary XDP Connector PinOut

Table below documents the pinout of Secondary XDP connector.

Table 46-10. Secondary XDP Connector Pinout (Sheet 1 of 2)

Pin	XDP Signal Name	Target Signal	I/O	Device	Pin	XDP Signal Name	Target Signal	I/O	Device
1	GND	GND	NA		2	GND	GND	NA	
3	OBSFN_A0	Open	NA		4	OBSFN_C0	GPP_E0 / SATAXPCIE0 / SATAGP0	I	PCH
5	OBSFN_A1	Open	NA		6	OBSFN_C1	GPP_F4 / SATAXPCIE7 / SATAGP7	I	PCH
7	GND	GND	NA		8	GND	GND	NA	
9	OBSDATA_A0	GPP_E1 / SATAXPCIE1 / SATAGP1	I	PCH	10	OBSDATA_C0	GPP_E9 / USB2_OC0#	I	PCH
11	OBSDATA_A1	GPP_E2 / SATAXPCIE2 / SATAGP2	I	PCH	12	OBSDATA_C1	GPP_E10 / USB2_OC1#	I	PCH
13	GND	GND	NA		14	GND	GND	NA	
15	OBSDATA_A2	GPP_E3 / CPU_GP0	I	PCH	16	OBSDATA_C2	GPP_E11 / USB2_OC2#	I	PCH
17	OBSDATA_A3	GPP_E4 / DEVSLP0	I	PCH	18	OBSDATA_C3	GPP_E12 / USB2_OC3#	I	PCH
19	GND	GND	NA		20	GND	GND	NA	
21	OBSFN_B0	Open	NA		22	OBSFN_D0	Open	NA	
23	OBSFN_B1	Open	NA		24	OBSFN_D1	Open	NA	
25	GND	GND	NA		26	GND	GND	NA	
27	OBSDATA_B0	GPP_E5 / DEVSLP1	I	PCH	28	OBSDATA_D0	GPP_F0 / SATAXPCIE3 / SATAGP3	I	PCH
29	OBSDATA_B1	GPP_E6 / DEVSLP2	I	PCH	30	OBSDATA_D1	GPP_F1 / SATAXPCIE4 / SATAGP4	I	PCH
31	GND	GND	NA		32	GND	GND	NA	
33	OBSDATA_B2	GPP_E7 / CPU_GP1	I	PCH	34	OBSDATA_D2	GPP_F2 / SATAXPCIE5 / SATAGP5	I	PCH
35	OBSDATA_B3	GPP_E8 / SATALED#	I	PCH	36	OBSDATA_D3	GPP_F3 / SATAXPCIE6 / SATAGP6	I	PCH
37	GND	GND	NA		38	GND	GND	NA	

**Table 46-10. Secondary XDP Connector Pinout (Sheet 2 of 2)**

Pin	XDP Signal Name	Target Signal	I/O	Device	Pin	XDP Signal Name	Target Signal	I/O	Device
39	HOOK0	RSMRST#	I	PCH	40	ITPCLK/HOOK4 ¹	Open	NA	
41	HOOK1	Open	NA		42	ITPCLK#/HOOK5	Open	NA	
43	VCC_OBS_AB	PCH v1.0A	NA	system	44	VCC_OBS_CD	PCH v1.0A	NA	system
45	HOOK2	Open	NA		46	HOOK6/RESET#	Open	NA	
47	HOOK3 ¹	Open	NA		48	HOOK7/DBR#	Open	NA	
49	GND	GND	NA		50	GND	GND	NA	
51	SDA ¹	Open	NA		52	TDO	Open	NA	
53	SCL ¹	Open	NA		54	TRSTn	Open	NA	
55	TCK1	Open	NA		56	TDI	Open	NA	
57	TCK0	Open	I		58	TMS	Open	NA	
59	GND	GND	NA		60	GND ² (XDP_PRESENT#)	GND	NA	

Notes:

1. These signals are optional, can be left as OPEN/No-Connect.
2. Connect pin 60 to GND when it is not used to indicate the presence of ITP-XDP style tool.

Table 46-11. Secondary XDP Connector Pinout (Sheet 1 of 2)

Pin	XDP Signal Name	Target Signal	I/O	Device	Pin	XDP Signal Name	Target Signal	I/O	Device
1	GND	GND	NA		2	GND	GND	NA	
3	OBSFN_A0	Open	NA		4	OBSFN_C0	GPP_E12 / USB2_OC3#	I	Coffee Lake
5	OBSFN_A1	Open	NA		6	OBSFN_C1	GPP_E3 / CPU_GP0	I	Coffee Lake
7	GND	GND	NA		8	GND	GND	NA	
9	OBSDATA_A0	GPP_E4 / DEVSLP0	I	Coffee Lake	10	OBSDATA_C0	GPP_D17 / DMIC_CLK1	I	Coffee Lake
11	OBSDATA_A1	GPP_E5 / DEVSLP1	I	Coffee Lake	12	OBSDATA_C1	GPP_D18 / DMIC_DATA1	I	Coffee Lake
13	GND	GND	NA		14	GND	GND	NA	
15	OBSDATA_A2	GPP_E6 / DEVSLP2	I	Coffee Lake	16	OBSDATA_C2	GPP_D19 / DMIC_CLK0	I	Coffee Lake
17	OBSDATA_A3	GPP_E7 / CPU_GP1	I	Coffee Lake	18	OBSDATA_C3	GPP_D20 / DMIC_DATA0	I	Coffee Lake
19	GND	GND	NA		20	GND	GND	NA	
21	OBSFN_B0	Open	NA		22	OBSFN_D0	Open	NA	
23	OBSFN_B1	Open	NA		24	OBSFN_D1	Open	NA	
25	GND	GND	NA		26	GND	GND	NA	
27	OBSDATA_B0	GPP_E8 / SATALED#	I	Coffee Lake	28	OBSDATA_D0	GPP_D23 / I2S_MCLK	I	Coffee Lake
29	OBSDATA_B1	GPP_E9 / USB2_OCO#	I	Coffee Lake	30	OBSDATA_D1	GPP_E0 / SATAXPCIE0 / SATAGPO	I	Coffee Lake

**Table 46-11. Secondary XDP Connector Pinout (Sheet 2 of 2)**

Pin	XDP Signal Name	Target Signal	I/O	Device	Pin	XDP Signal Name	Target Signal	I/O	Device
31	GND	GND	NA		32	GND	GND	NA	
33	OBSDATA_B2	GPP_E10 / USB2_OC1#	I	Coffee Lake	34	OBSDATA_D2	GPP_E1 / SATAXPCIE1 / SATAGP1	I	Coffee Lake
35	OBSDATA_B3	GPP_E11 / USB2_OC2#	I	Coffee Lake	36	OBSDATA_D3	GPP_E2 / SATAXPCIE2 / SATAGP2	I	Coffee Lake
37	GND	GND	NA		38	GND	GND	NA	
39	HOOK0	RSMRST#	I	Coffee Lake	40	ITPCLK/HOOK4 ¹	Open	NA	
41	HOOK1	Open	NA		42	ITPCLK#/HOOK5	Open	NA	
43	VCC_OBS_AB	PCH v1.0A	NA	system	44	VCC_OBS_CD	PCH v1.0A	NA	system
45	HOOK2	Open	NA		46	HOOK6/RESET#	Open	NA	
47	HOOK3 ¹	Open	NA		48	HOOK7/DBR#	Open	NA	
49	GND	GND	NA		50	GND	GND	NA	
51	SDA ¹	Open	NA		52	TDO	Open	NA	
53	SCL ¹	Open	NA		54	TRSTn	Open	NA	
55	TCK1	Open	NA		56	TDI	Open	NA	
57	TCK0	Open	I		58	TMS	Open	NA	
59	GND	GND	NA		60	GND ² (XDP_PRESENT#)	GND	NA	

Notes:

1. These signals are optional, can be left as OPEN/No-Connect.
2. Connect pin 60 to GND when it is not used to indicate the presence of ITP-XDP style tool.

46.1.2.5 Secondary CMC PinOut

Table 46-12 documents the pinout of Secondary CMC connector.

Table 46-12. Secondary CMC Connector Pinout (Sheet 1 of 2)

Pin	CMC Signal Name	Target Signal	I/O	Device	Pin	CMC Signal Name	Target Signal	I/O	Device
1	OBSDATA_0	GPP_E1 / SATAXPCIE1 / SATAGP1	I	PCH	2	OBSDATA_8	GPP_E9 / USB2_OC0#	I	PCH
3	OBSDATA_1	GPP_E2 / SATAXPCIE2 / SATAGP2	I	PCH	4	OBSDATA_9	GPP_E10 / USB2_OC1#	I	PCH
5	OBSDATA_2	GPP_E3 / CPU_GPO	I	PCH	6	OBSDATA_10	GPP_E11 / USB2_OC2#	I	PCH
7	OBSDATA_3	GPP_E4 / DEVSLP0	I	PCH	8	OBSDATA_11	GPP_E12 / USB2_OC3#	I	PCH
9	OBSDATA_4	GPP_E5 / DEVSLP1	I	PCH	10	OBSDATA_12	GPP_F0 / SATAXPCIE3 / SATAGP3	I	PCH
11	OBSDATA_5	GPP_E6 / DEVSLP2	I	PCH	12	OBSDATA_13	GPP_F1 / SATAXPCIE4 / SATAGP4	I	PCH

**Table 46-12. Secondary CMC Connector Pinout (Sheet 2 of 2)**

Pin	CMC Signal Name	Target Signal	I/O	Device	Pin	CMC Signal Name	Target Signal	I/O	Device
13	OBSDATA_6	GPP_E7 / CPU_GP1	I	PCH	14	OBSDATA_14	GPP_F2 / SATAXPCIE5 / SATAGP5	I	PCH
15	OBSDATA_7	GPP_E8 / SATALED#	I	PCH	16	OBSDATA_15	GPP_F3 / SATAXPCIE6 / SATAGP6	I	PCH
17	OBS_CLK_1P	GPP_E0 / SATAXPCIE0 / SATAGP0	I	PCH	18	OBS_CLK_2P	GPP_F4 / SATAXPCIE7 / SATAGP7	I	PCH
19	GND	GND	NA		20	OBS_CLK_2N	Open	NA	
21	OBS_CLK_1N	Open	NA		22	VCCOBS_AB	Open	NA	
23	XDP_PRESENT_CPU	Open	NA		24	XDP_PRESENT_P CH	Open	NA	
25	HOOK[3]	Open	NA		26	HOOK[6]	Open	NA	
27	HOOK[0]	Open	NA		28	XDP_TRST#	Open	NA	
29	XDP_TDI	Open	NA		30	XDP_TMS	Open	NA	
31	XDP_TCK1	Open	NA		32	XDP_TCK0	Open	NA	
33	XDP_PREQ#	Open	NA		34	XDP_PRDY#	Open	NA	
35	XDP_TDO	Open	NA						

46.1.3 Intel® DCI Implementation

Intel® DCI (Direct Connect Interface) is an Intel Technology that allows debug access by re-purposing a USB 3.0 port. The advantage is debug functions and trace features can be connected using existing USB3 ports, rather than the usual additional connectors. If properly supported, many debug functions can be implemented “closed chassis”. The DCI connection supports run-control debug, validation, trace, DMA, OS Debug and scripting.

DCI is implemented using two primary transport topologies: Intel® DCI-OOB (formerly BSSB), and Intel® DCI-Debug Class (formerly DbC).

The following sub sections cover the requirements to implement Intel® DCI for supporting closed-chassis debug on the platform.

All USB3 ports support Intel DCI. USB3 Port 1 additionally supports OTG. If the OTG function is not used, please pull down the USB2_ID pin to program the function properly.

This sections describes the debug hook routing requirement for platforms using Intel DCI without an XDP60 or CMC connector.

It is important to maintain the merged JTAG circuitry for proper Intel DCI functionality. Route the JTAG pins, HOOK pins according to the [Table 46-10](#) and [Figure 46-14](#):

Figure 46-10. Connector Less Routing Topology

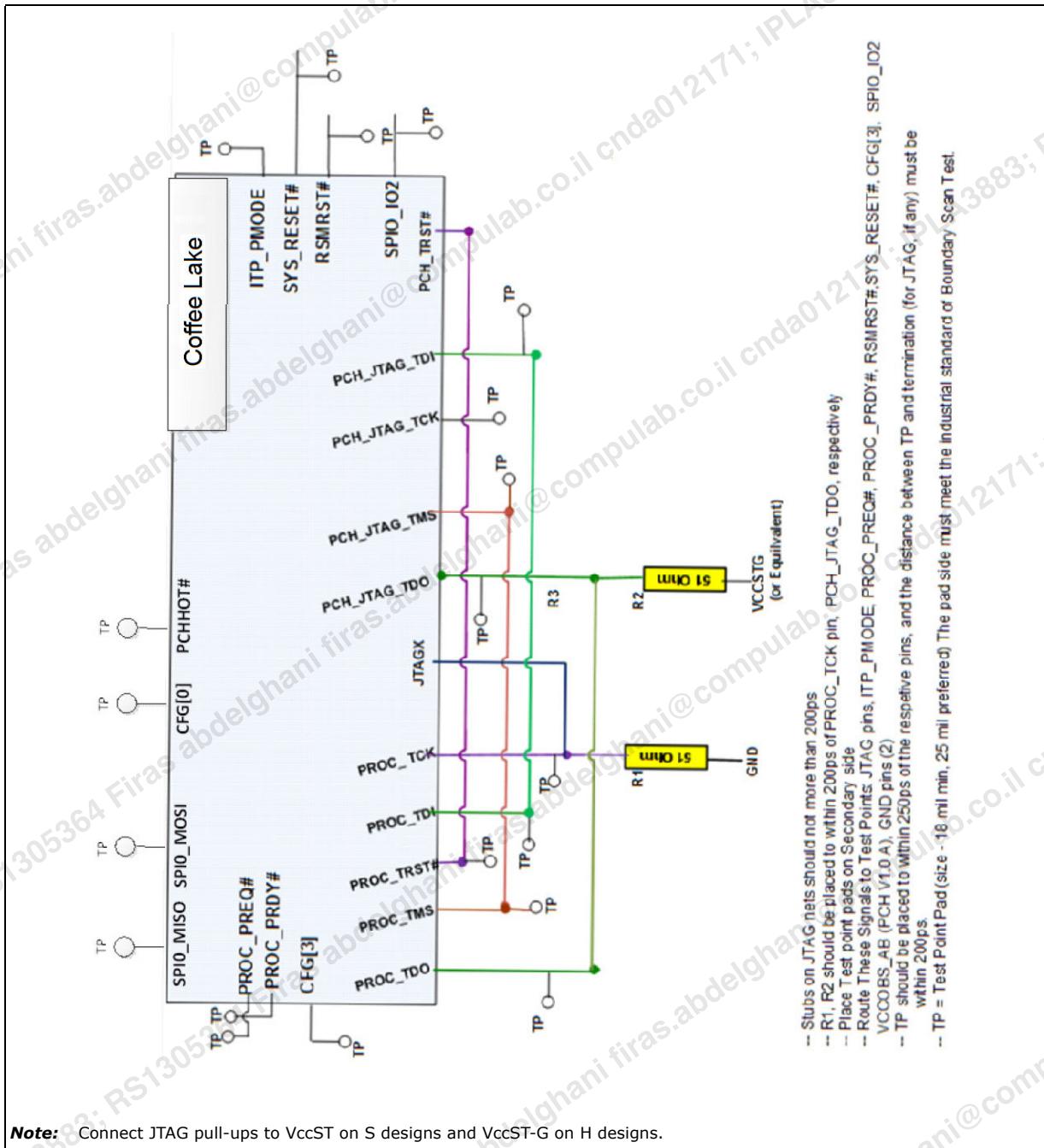
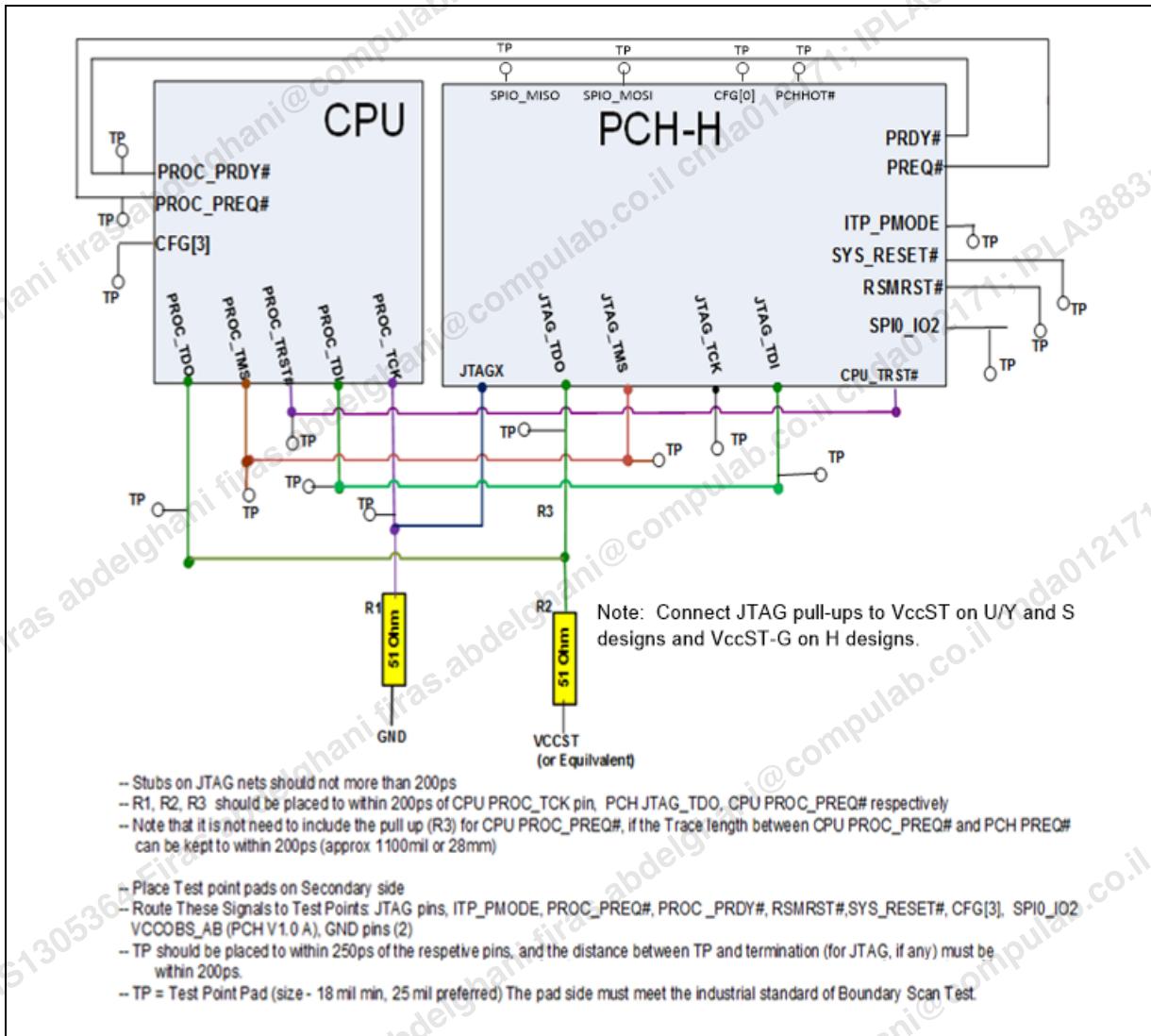


Figure 46-11. Connector Less Routing Topology


**Table 46-13. Connector Less Debug Hooks Routing Guidelines**

Pin/Signal	Routing Rules	Notes
PROC_TDI, PROC_TDO, PROC_TMS, PROC_TCK, PROC_TRST#, PCH_JTAG_TCK PCH_JTAG_TDI PCH_JTAG_TDO, PCH_JTAG_TMS, JTAGX, PCH_TRST#	<ul style="list-style-type: none"> Route these signals to Test Points according to Figure 46-13; Stub Length: 200ps (approx 1100 mil or 28mm) Maximum Trace length: 1ns (approx 6000 mil or 154mm) PROC_TCK Termination: <ul style="list-style-type: none"> 51 ohm +/- 5% pull down to GNG (Ground) Placed to within 200ps (1100 mil) or PROC_TCK pin PCH_JTAG_TDO Termination: <ul style="list-style-type: none"> 51ohm +/- 5% pull up to VccSTG or equivalent. Placed to within 200ps (1100 mil) or PCH_JTAG_TDO pin Test Point Pad Size: 18 mil minimum, preferred 25 mil maximum Test Points Placement: placed to within 250ps of the repetitive Coffee Lake pins, and the distance between TP and termination (if any) must be within 200ps. Refer Section 46.1.7 for additional routing guidelines on Test Points requirement for Intel® Silicon View Technology DFM HVM Test Solution. Refer to Section 46.1.6 for additional PCB layout rules. 	
RSMRST#, PROC_PREQ#, PROC_PRDY#, CFG[3], SPIO_IO2, SYS_RESET#, ITP_PMODE	<ul style="list-style-type: none"> Route these signals to Test Points according to Figure 46-13 Test Point Pad Size: Minimum 18mil, preferred 28 mil Refer RSMRST#, CFG[3], SPI_IO2, SYS_RESET# in their respective sections for additional routing guidelines and termination or strapping requirement. Refer Section 46.1.7 for additional routing guidelines on Test Points requirement for Intel® Silicon View Technology DFM HVM Test Solution. 	
GND, VCCOBS_AB	<ul style="list-style-type: none"> Route PCH V1.0 A Rail or equivalent voltage rail to a test point pad. Route two ground (GND) pins directly to a GND plane through individual vias. Test Point Pad Size: Minimum 18mil, preferred 28 mil Refer Section 46.1.7 for additional routing guidelines on Test Points requirement for Intel® Silicon View Technology DFM HVM Test Solution. 	
JTAG_ODT_Disable	<ul style="list-style-type: none"> Let Float 	
SML1ALERT#/ PCHHOT#/GPP_B23	<ul style="list-style-type: none"> If USB 3.0 Port 1 is used for 4-wire DCI.OOB (BSSB), and alternate functionality is also used on the pin, pull up to V3.3S with >100K resistor to avoid noise. If USB 3.0 Port 1 is used for DCI.OOB (BSSB) 4-wire BSSB, and NO alternate functionality is used, leave float. If DCI.OOB (BSSB) 2+2 functionality is used, pull up to V3.3S with a 4.7K resistor. 	

Pin/Signal	Routing Rules	Notes
CPU: PROC_TDI, PROC_TDO, PROC_TMS, PROC_TCK, PROC_TRST#, PCH-H: JTAG_TCK, JTAG_TDI, JTAG_TDO, JTAG_TMS, JTAGX, CPU_TRST#	<ul style="list-style-type: none"> Route these signals according to Figure 46-13 Stub Length: 200ps (approx 1100mil or 28mm) Maximum Trace length: 1ns (approx 6000mil or 154mm)) PROC_TCK Termination: <ul style="list-style-type: none"> 51 Ω +/- 5% pull down to GND (Ground) Placed to within 200ps (1100 mil) or PROC_TCK pin PCH-H JTAG_TDO Termination: <ul style="list-style-type: none"> 51Ω +/- 5% pull up to VccST rail or equivalent. Placed to within 200ps (1100 mil) or PCH-H JTAG_TDO pin Test Point Pad Size: 18 mil minimum, preferred 25 mil maximum Test Points Placement: placed to within 250ps of the repetitive Coffee Lake pins, and the distance between TP and termination (if any) must be within 200ps. Refer Section 46.1.7 for additional routing guidelines on Test Points requirement for Intel® Silicon View Technology DFM HVM Test Solution. Refer to Section 46.1.6 for additional PCB layout rules. 	



Pin/Signal	Routing Rules	Notes
CPU PROC_PREQ# PROC_PRDY#	<ul style="list-style-type: none">Route these signals according to Figure 46-13.Stub Length: 200ps (approx 1100mil or 28mm)Maximum Trace length: 2.5ns (approx 15000mil or 381mm), should minimize the trace length whenever possible.	
PCH PREQ# PRDY#	<ul style="list-style-type: none">Test Point Pad Size: 18 mil minimum, preferred 25 mil maximumTest Points Placement: placed to within 250ps of the repetitive Coffee Lake pins, and the distance between TP and termination (if any) must be within 200ps.Refer Section 46.1.7 for additional routing guidelines on Test Points requirement for Intel® Silicon View Technology DFM HVM Test Solution.Refer to Section 46.1.6 for additional PCB layout rules.	
PCH-H: RSMRST#, SPIO_IO2, SYS_RESET#, ITP_PMODE	<ul style="list-style-type: none">Route these signals to Test Points according to Figure 46-13Test Point Pad Size: Minimum 18mil, preferred 28 milRefer RSMRST#, CFG[3], SPI_IO2, SYS_RESET# in their respective sections for additional routing guidelines and termination or strapping requirement.Refer Section 46.1.7 for additional routing guidelines on Test Points requirement for Intel® Silicon View Technology DFM HVM Test Solution.	
CPU: CFG[3]		
GND, VCCOBS_AB	<ul style="list-style-type: none">Route PCH V1.0 A Rail or equivalent voltage rail to a test point pad.Route two ground (GND) pins directly to a GND plane through individual vias.Test Point Pad Size: Minimum 18mil, preferred 28 milRefer Section 46.1.7 for additional routing guidelines on Test Points requirement for Intel® Silicon View Technology DFM HVM Test Solution.	
JTAG_ODT_Disable	<ul style="list-style-type: none">Let Float	
SML1ALERT#/ PCHHOT#/GPP_B23	<ul style="list-style-type: none">If USB 3.0 Port 1 is used for 4-wire DCI.OOB (BSSB), and alternate functionality is also used on the pin, pull up to V3.3S with >100K resistor to avoid noise.If USB 3.0 Port 1 is used for DCI.OOB (BSSB) 4-wire BSSB, and NO alternate functionality is used, leave float.	

46.1.3.1 Intel® DCI OOB Overview

Intel® DCI-OOB is implemented using a proprietary electrical transport over the USB3 port. The USB3 pins are used, but do not use USB3 electrical signaling. The following sections describe tool considerations and board schematic considerations.

It is only required to support Intel® DCI-OOB on one external connector. The least complex and least expensive solution is to use an existing USB3 Type A connector which does not use any retimer solution. If only USB Type C is available, then the section describes configurations appropriate to make Intel® DCI-OOB operate properly.

Advantage: Intel® DCI-OOB is used when debug connections need to survive power transitions to S0iX and Sx states. Starts operation almost immediately upon boot start. Additionally, if Intel® DCI-OOB is connected from a cold boot, no BIOS enabling is needed.

Disadvantage: Transport operates at a considerably lower frequency than Intel® DCI-Debug class.

46.1.3.1.1 Interface Tool Considerations for Intel® DCI OOB Support over USB3

Intel® DCI-OOB requires a special debug adaptor called the Closed Chassis Adapter (CCA). From a user perspective, the software automatically configures to use the new Intel® DCI-OOB interface.



46.1.3.1.2 Signaling Considerations for Intel® DCI OOB Support over USB3

For Intel® DCI-OOB Hosting DCI functionality to work properly in the system, the following signaling requirements must be met by the platform design:

- Any external pull-down resistor on the SoC TRST_N trace must be depopulated. This is especially important in systems migrating from open-chassis MIPI60 operation.
- All the devices in Intel® DCI-OOB Hosting signal path must be designed to support Intel® DCI-OOB signaling. The proprietary Intel® DCI-OOB signaling is single-ended CMOS which must be preserved for this debug technology to operate properly.
 - Any components placed in this path must allow the CMOS single ended like signaling to pass.
 - In general, this can rule out any active switches, re-timers, and re-drivers in this path.
 - CMCs, EMI inductors/ferrite beads (Common Mode Chokes), negatively impact Intel® DCI-OOB performance. If not needed for EMI suppression, remove or short out. These filters aren't needed for USB functionality but are used to reduce radio interference. CMCs may interfere with OOB signal integrity by changing the maximum effective operating frequency of the data channel. Remove from the SSRx signals and replace with $0\ \Omega$ resistors (or wires/solder bridges) if higher OOB transport frequencies are needed.
 - RX Coupling capacitors: Some designs implement AC coupling caps on the inbound RX SS pin. This breaks Intel® DCI-OOB and violates the USB standards specification. Capacitors are placed only on the TX SS signals.
 - Signaling for Intel® DCI-OOB operates at maximum of 1.0V.

46.1.3.1.3 Intel® DCI OOB Configurations Supporting USB3 Type A

For Intel® DCI-OOB Hosting DCI functionality to work properly in the system, proper signaling as described in previous section must be preserved. For many USB3 Type A implementations, no re-timer device is required. If a re-timer is required, it will stop OOB operation.

46.1.3.1.4 Intel® DCI OOB Configurations Supporting USB Type-C Implementations

Support for alternate functions such as Display Port and plug reverse require an external MUX device which complicates the Intel® DCI-OOB design. Additionally, re-timer devices, which improve signal fidelity, block OOB signaling and special devices are needed to remedy the situation. Try to use Type A for DCI as much as possible. For design without Type-C, please reserve an unused USB3 port and route it to test points for soldering a type A connector when DCI.OOB is necessary. DCI.OOB usage will be reduced because of the introduction of DCI.USB2. So the rework should be minimal.

46.1.3.2 DCI.USB2/DCI.USB3

Intel® DCI-Debug Class is implemented using standard USB3 Super Speed/ USB2 High Speed electrical and transport protocol. There are no additional electrical channel or connection requirements for using DCI-USB as the standard USB3 Super Speed/USB2



High Speed channel is used. A standard USB3/USB2 cable can be used for connecting the Host PC and the SUT. No special interface box is required. Bear in mind that only designs paired with Cannon Lake PCH will have DCI.USB2 feature

USB3 Advantage: Much higher transport speeds.

USB3 Disadvantage: Starts later in boot process so some early messages and unlock capabilities are not available. Does not operate through power sequences.

USB2 Advantage: Higher speed than DCI-OOB. No special interface box is required. Can even trace in S5.

USB2 Disadvantage: There are some usages that DCI-USB2 cannot handle. Those cases will be handled by Intel using DCI-OOB

46.1.3.2.1 **Signaling Considerations for Intel® DCI Direct Connect Support over USB3/USB2**

The controllers and multiplexers in the signal path of the USB3/USB2 pins must be powered when Intel DCI "Direct Connect" is in use for the signals to pass. Standard USB3/USB2 signaling is utilized.

46.1.3.3 **Thunderbolt™ Configurations**

Alpine Ridge does not directly support Intel.DCI.OOB. Refer [Chapter 11, "Thunderbolt™ Design Guidelines"](#) in this document supporting Thunderbolt Solutions for proper implementation.

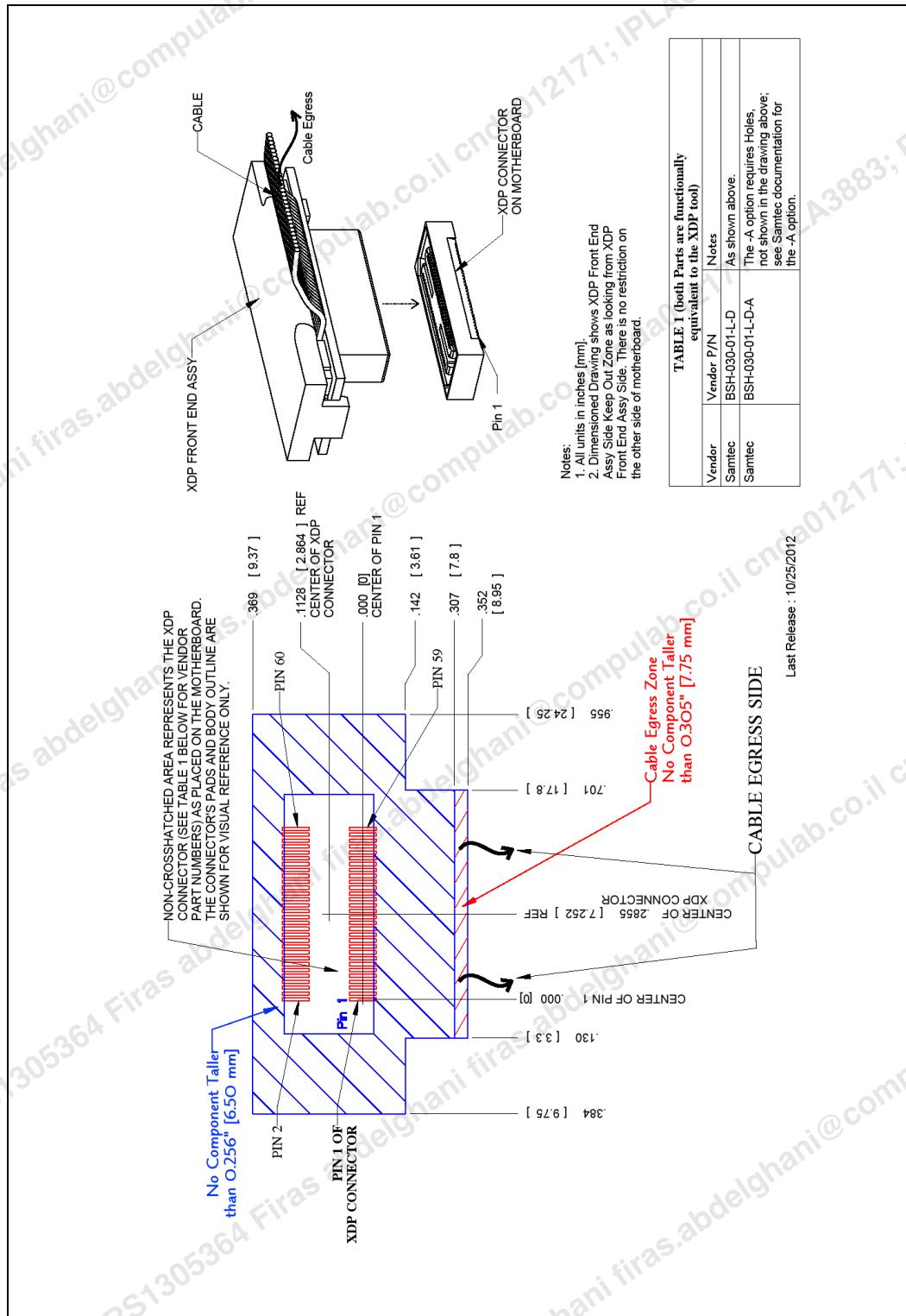
46.1.4 **eXtended Debug Port (XDP) Mechanical Specifications**

[Figure 46-12](#) illustrates the target system volume that must be reserved for the ITP-XDP to attach to the target system. It is recommended that the main ITP-XDP enclosure be securely attached to the target system to avoid damage to the ITP-XDP and the target system. Four 1/8 inch mounting holes are provided on the ITP-XDP to facilitate attachment with screws or cable ties.

The Intel ITP-XDP3 hardware unit has four half-inch by 1/16th inch slots for cable tie or velcro straps to secure the body of the ITP-XDP3 hardware unit to the chassis. Third party vendors run control tools would have different keepout volumes and securing features.



Figure 46-12.60-pin XDP Connector System Keep-Out Diagram





The placement of the XDP connector on the 2nd side should be avoided if possible. Among other reasons, it should be avoided due to the complexity of hand placing and soldering the device. Cap all vias near the XDP-connector pads in compliance with the Intel DFM Guidelines for capped vias. vias need to be capped not only around the XDP connector pads, but also specifically under the XDP connector body. Open vias under the XDP connector can cause shorts.

Contact your Intel representative for a formal review of the mechanical placement and layout of the system.

46.1.5 Chassis Mount Connector (CMC) Mechanical Specifications

Chassis Mount Connector (CMC) is a compact connecting solution developed by Intel for Coffee Lake platform debug. CMC has a much smaller keep-out than the standard 60 pin XDP connector. It utilizes a motherboard through-hole for mounting and makes contact with pads located and routed around the mounting hole via the CMC connector. There are two versions of CMC adapters: the CMC Merged adapter (primary CMC) offers the same DFX accessibility (with the exception of SMBus) as the standard 60-pin XDP connector and the CMC OBS adapter (secondary CMC) provide access to OBS signals via paddle-board.

46.1.5.1 Primary Chassis Mount Connector (CMC) Mechanical Drawings and Keep Out

The following diagrams illustrate the KOZ and KOV must be reserved for the Primary (Merged) CMC adapter on a Coffee Lake platform.

Note that an adapter (ITPCMCMERGEADAP1, MM#933664) to connect Primary CMC to XDP connector on the ITP hardware is required. This adapter can be ordered from <https://designIntools.intel.com/>.



Figure 46-13.Primary (Merged) CMC Gen 1 Keep out Specification

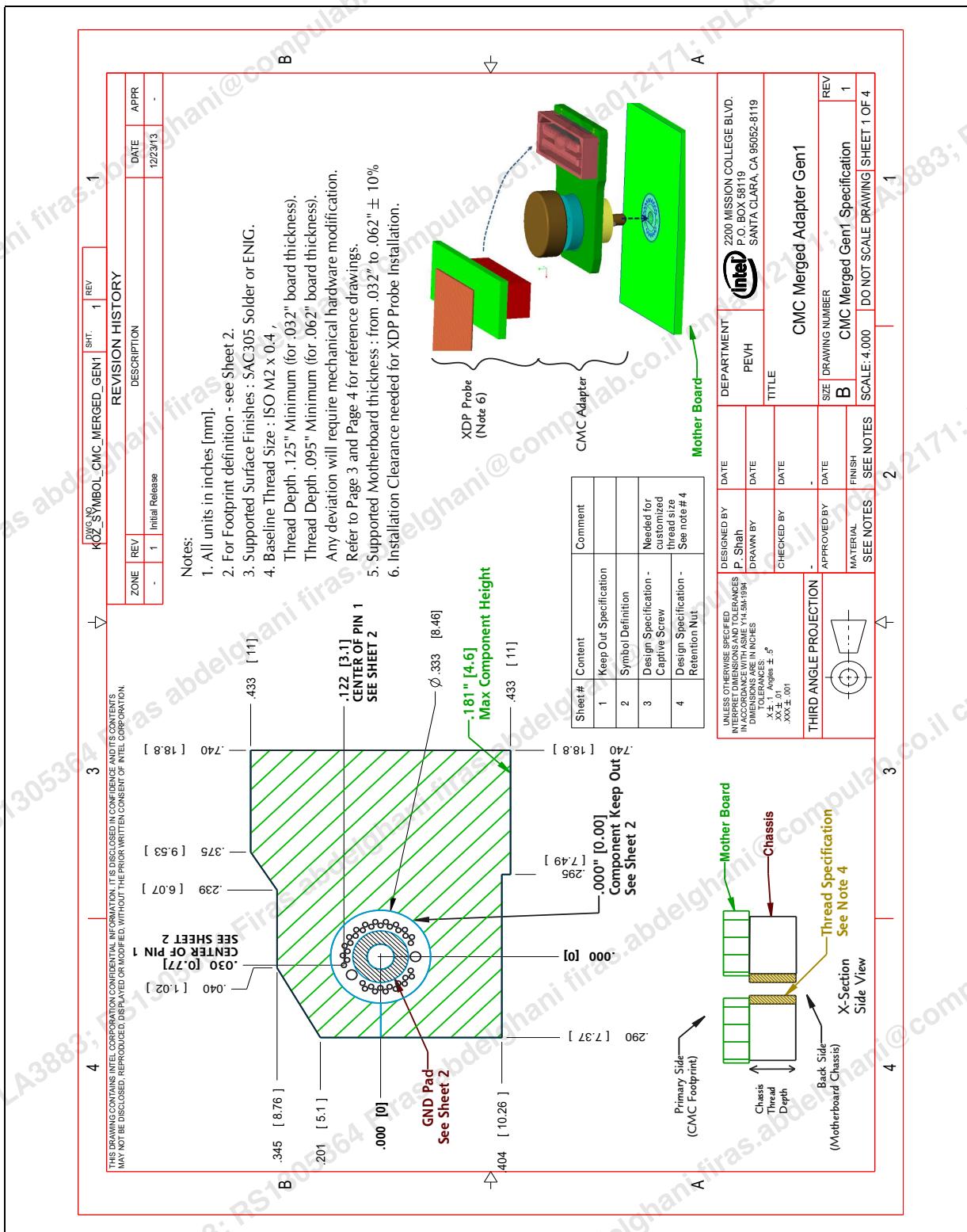


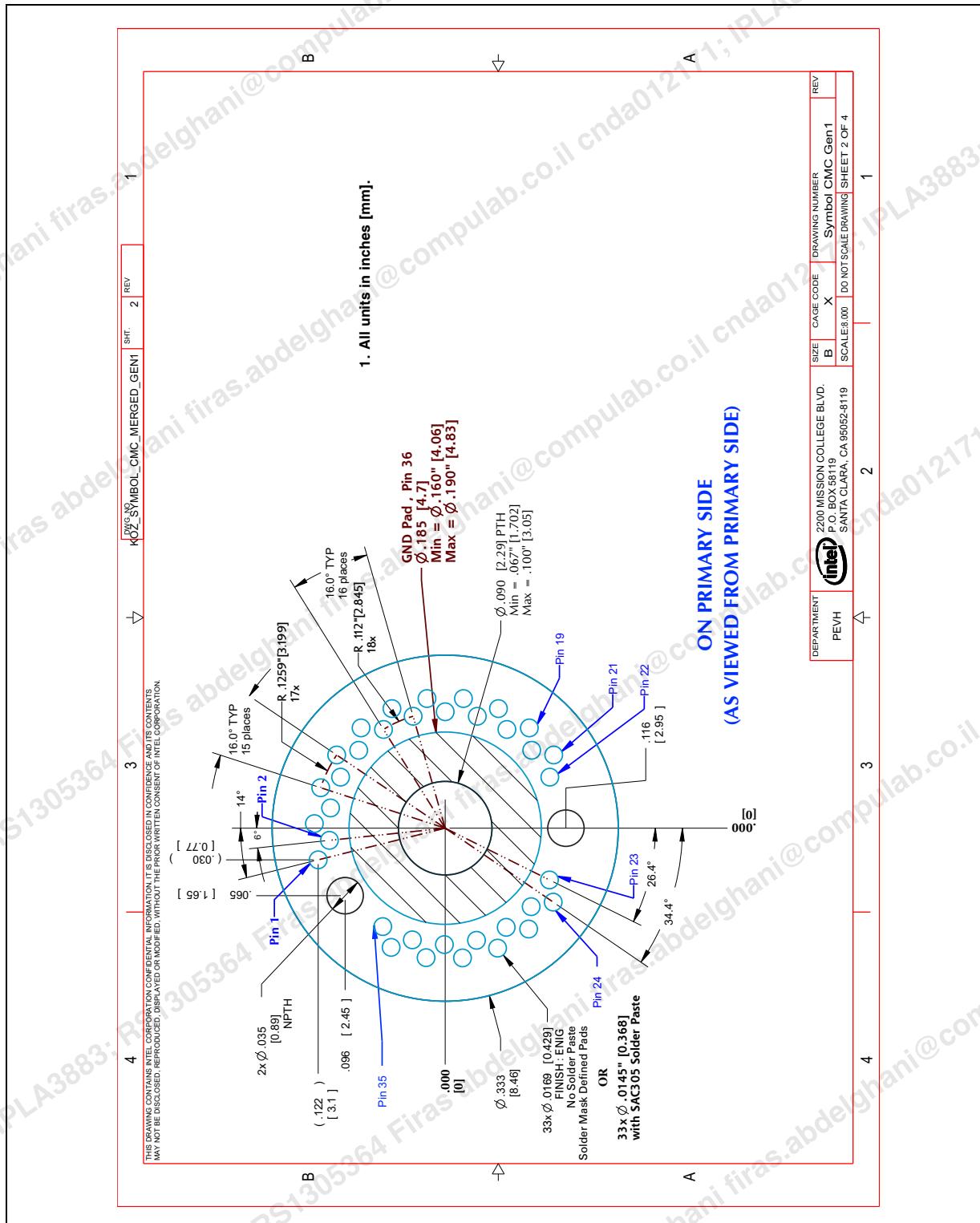
Figure 46-14.Primary (Merged) CMC Pads Layout (Primary Side)




Figure 46-15.CMC Gen 1 - Captive Screw

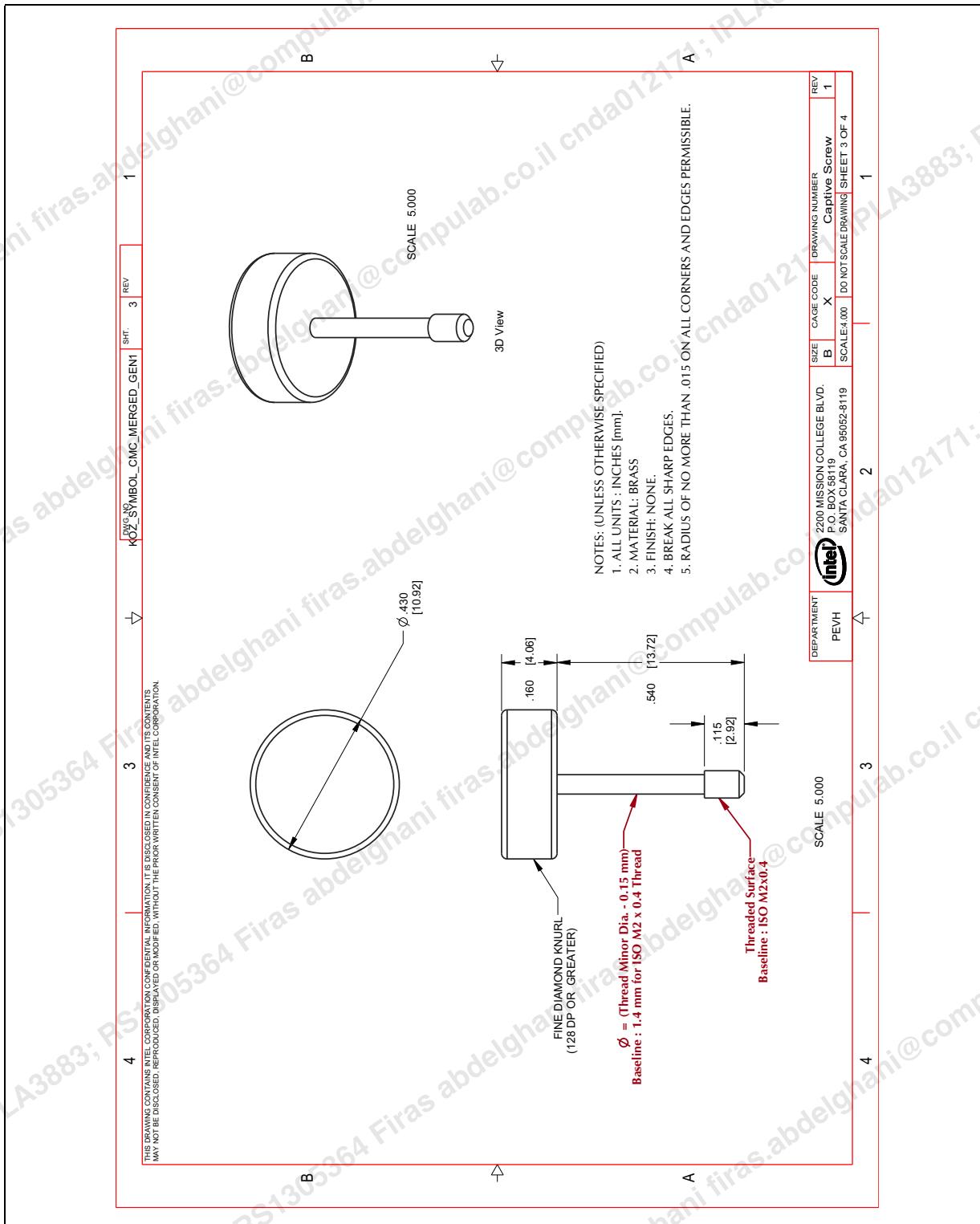
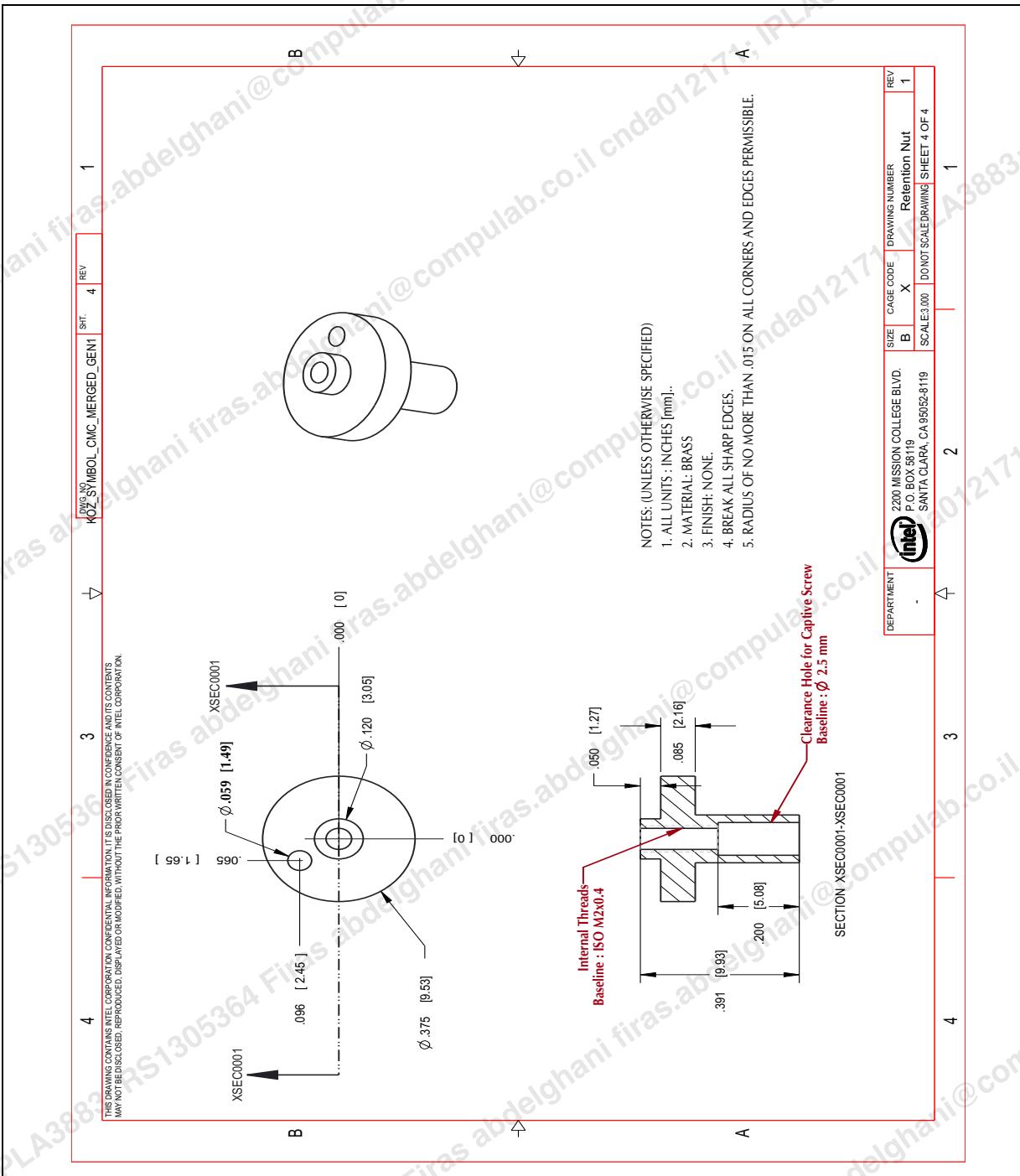


Figure 46-16.CMC Gen 1- Retention Nut


46.1.5.2 Secondary Chassis Mount Connector (CMC) Mechanical Drawings and Keep Out

The following diagrams illustrate the KOZ and KOV must be reserved for the Secondary (OBS) CMC attachment on a Coffee Lake platform.

Figure 46-17. Secondary CMC Keep Out Specification

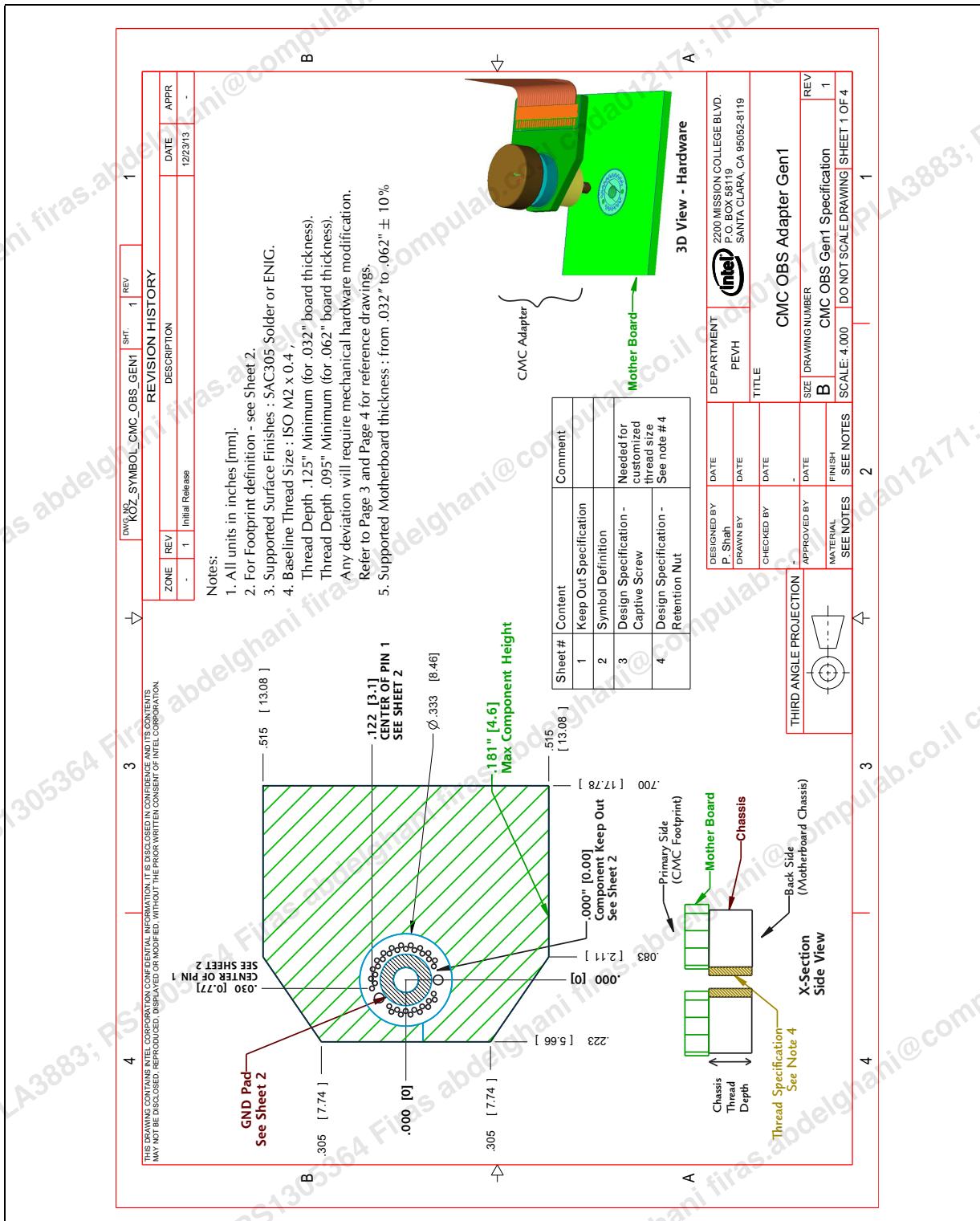
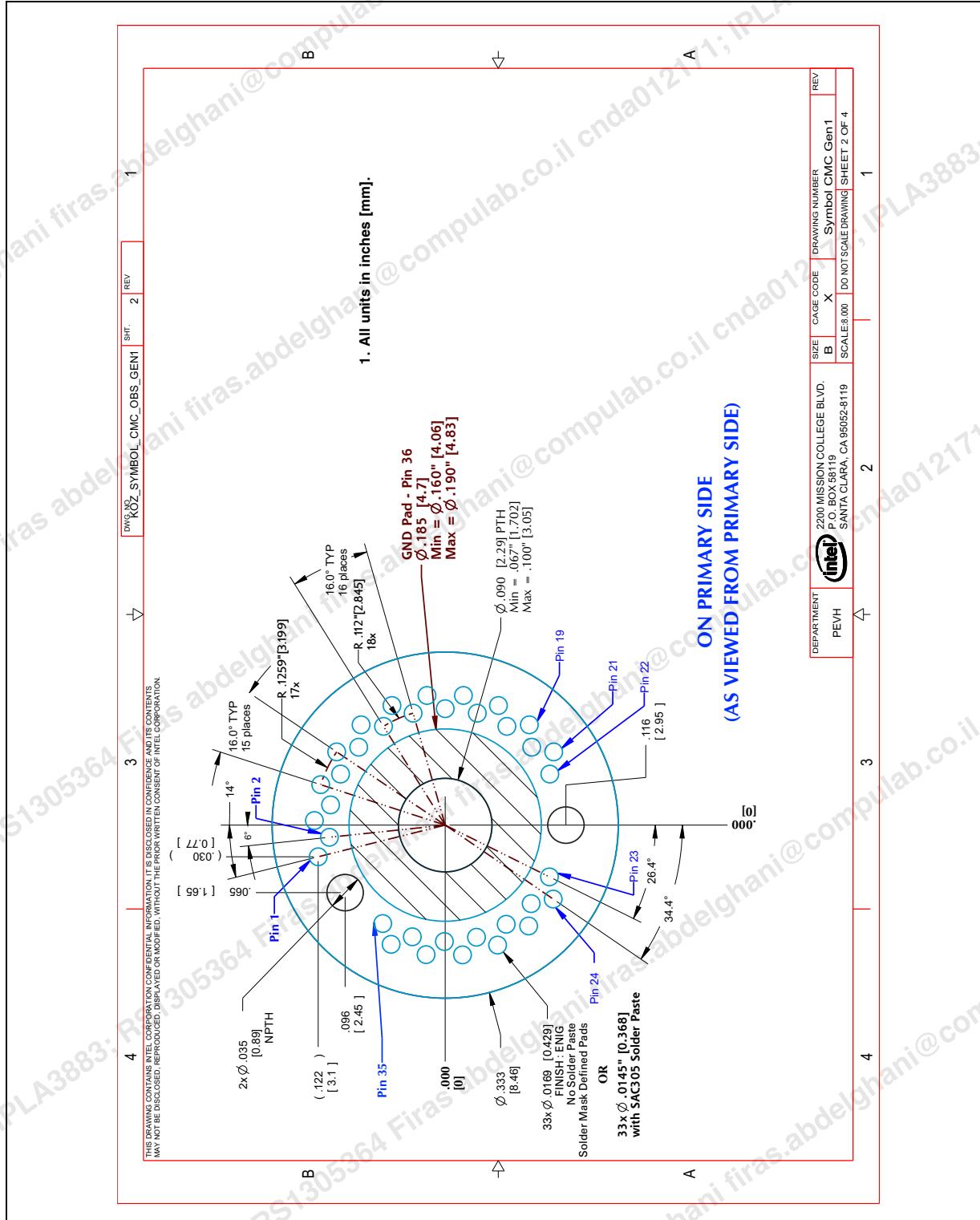


Figure 46-18. Secondary (OBS) CMC Pads Layout





Refers to [Figure 46-15](#) and [Figure 46-16](#) for the mechanical drawings of CMC Captive Screw and Retention Nut.

Note that An adapter (ITPCMCOBSADAP1, MM#933663) to connect Secondary OBS CMC to Logic Analyzer Interface connector is required. This adapter can be ordered from <https://designIntools.intel.com/>.

46.1.6 Additional Debug Port PCB Layout Guidelines

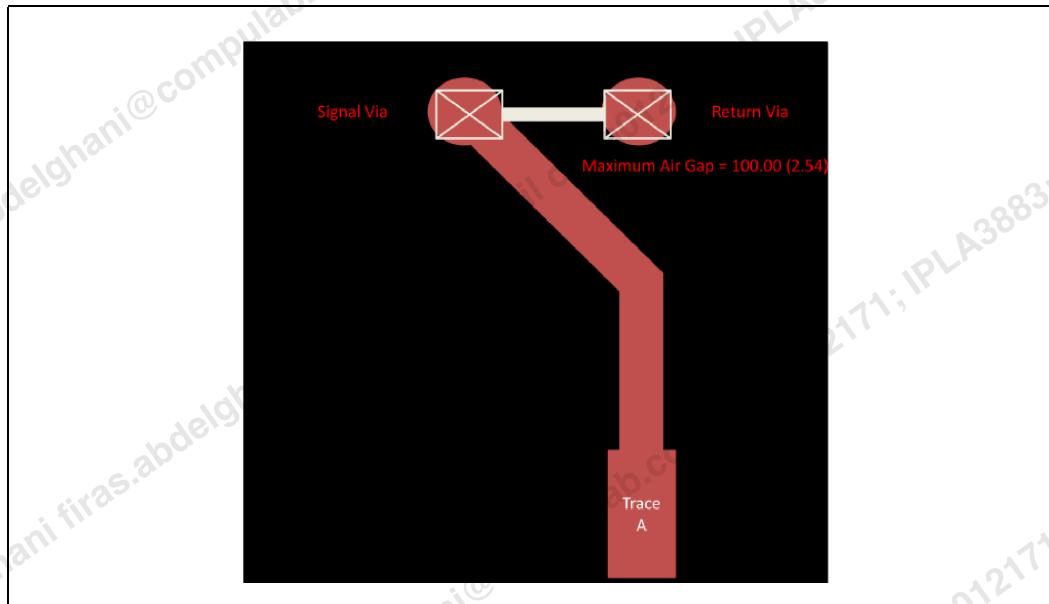
This section describes the general high speed layout guidelines must be followed for the debug port:

Electrical lengths of XDP traces are provided in units of flight time. Conversion of flight time to board-trace lengths is dependent on what layer routing occurs on, and the dielectric constant of the board materials for a specific design. Rule-of-thumb numbers can be derived by using 140 to 180ps/inch for outer layers of an FR4 product and 180ps/inch for inner layers

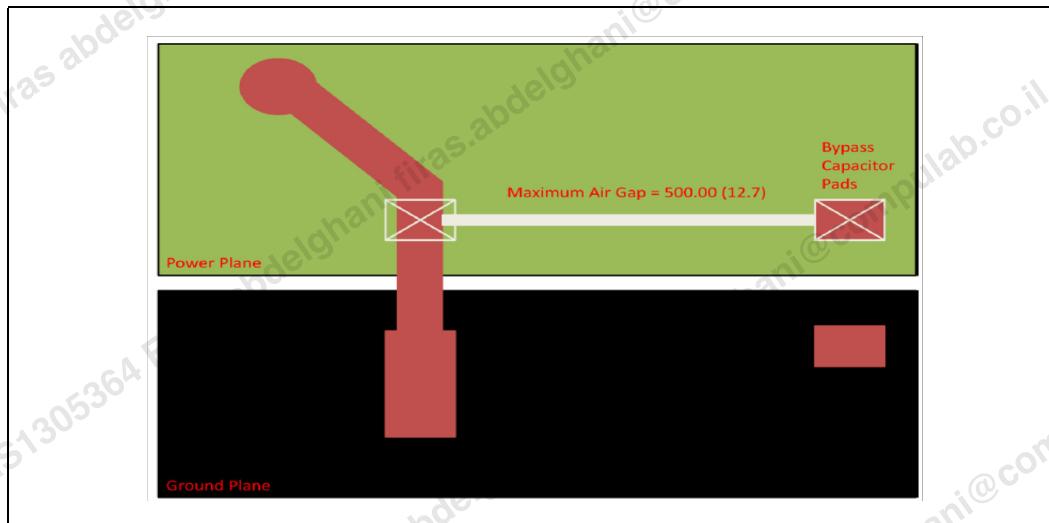
Trace Nominal Impedance for Debug Port JTAG signals, OBS pins, HOOK[3:0], HOOK[7:6], XDP_PRESENT#, I²C pins: 50 Ω ±17% nominal impedance. HOOK[5:4]: 100Ω (differential pair).

Unless indicated otherwise, Signals on the debug port should be routed with this in mind:

- Minimize the number of layer transitions and avoid plane split crossings imposed on each trace (ideally this will be zero). If return paths are well kept then the number of vias are nearly immaterial.
 - Clock signals (TCK, OBSFN_CD/OBS_CLK) are allowed maximum of 4 vias.
 - Clock signals are not allowed to route across splits or over voids.
- All signals except VCCOBS, GND and HOOK[5:4] pins must be referenced to ground (GND) plane.
- All signals except GND, VccOBS, and HOOK[0,1, 2, 3, 6, 7] pins must include ground-stitching/return vias near every layer transition. ground-stitching/return vias should be placed to within 0.1 inches (2.54mm) of the signal via.

Figure 46-19.Ground Stitching/Return Vias Example

- For situations where these signals are routed referenced to one or more power planes, include a bypass capacitor near every layer transition or plane split between the two referenced planes. bypass capacitor pads should be placed to within 0.5 inches (12.7mm) from the trace.

Figure 46-20.Bypass Capacitor

- Avoid sharing XDP bypass capacitors with other high-speed signals.
- For all signals, pull-up termination resistors should be located above a solid-power plane. If a solid-power plane does not exist at the required termination location, add a $0.1\mu F$ ceramic capacitor to GND on the pull-up voltage within 0.5 inches of termination resistor.

The length of any un-terminated stub on any TCK (1:0) or observation-port pin nets must be less than 200ps (1100 mil or 28mm) unless otherwise stated. The $51 \pm 5\%$ Ω recommendation in this document for signal termination has been proven to work on all recommended board impedances. JTAG and observation-port signals may optionally be terminated using the nominal-board impedance.

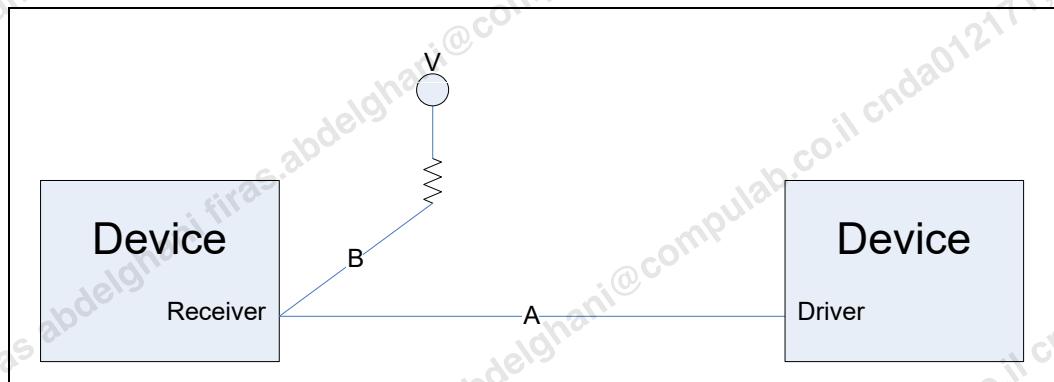
46.1.6.1 Termination Resistor Placement

Termination resistances are given, with tolerances, whenever appropriate. Tolerances are documented as within \pm of the percentage.

With few exceptions (noted specifically in their description), termination resistors must be close to the receiver. The topology, at the end of the chain, must be terminated in one of the following ways (in all cases) except those noted in their specific description.

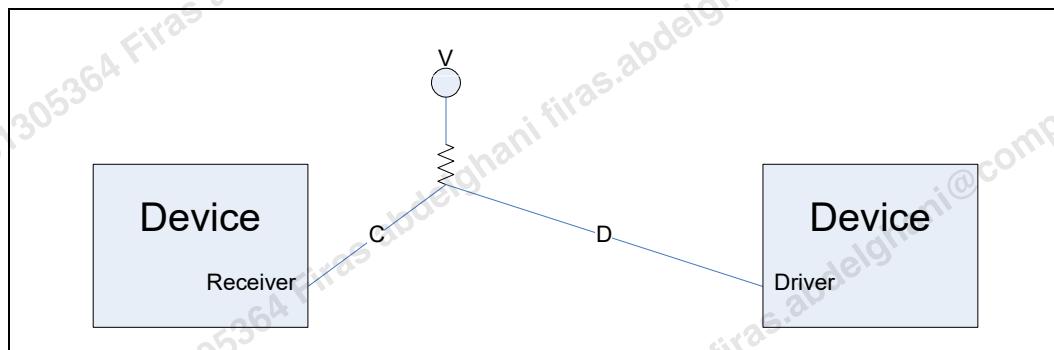
Preferred Debug Port termination Method: In the case of [Figure 46-21](#), where there is a termination after the last receiver, (A) must be smaller than any noted maximum routing length. There is no restriction for the length of (B) unless otherwise noted.

Figure 46-21.Termination after Last Receiver



Option 2 for XDP termination Method: [Figure 46-22](#) shows another method for termination that is equally valid. This is a termination prior to the end receiver where the maximum routing length of the signal must be less than the length of (D) + (C). (C) must be less than 200ps or noted stub length whichever is smaller.

Figure 46-22.Termination Prior to Last Receiver



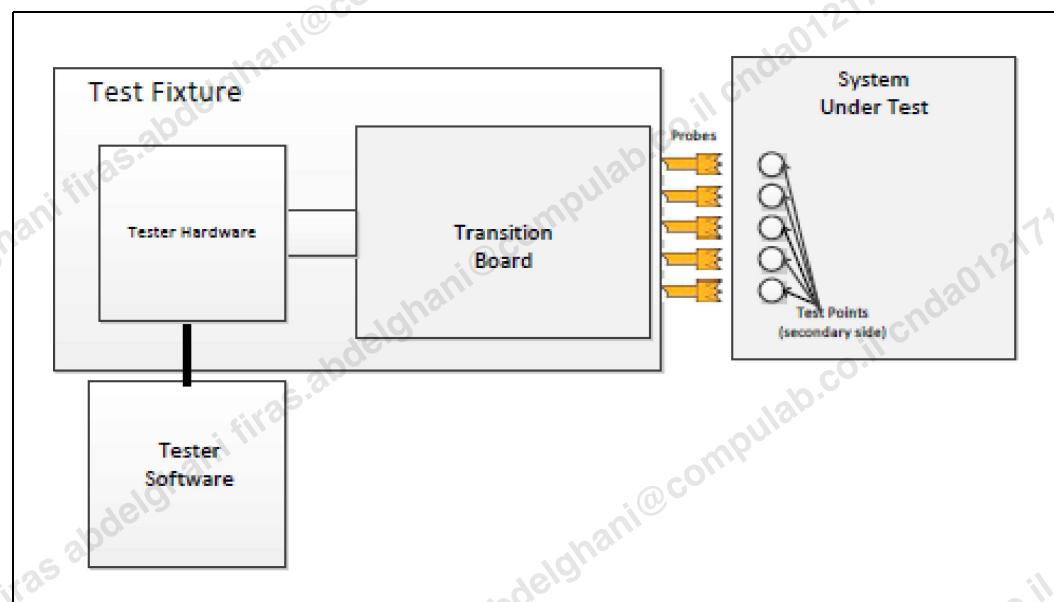
In both figures above, note that there may be other devices on the (A) or (D) routing of the signal if called for within this document.

46.1.7

Additional Routing Guidelines to support Intel® Silicon View Technology (Intel® SVT) based DFM HVM Test Solution

Intel enabled several third party JTAG vendors to design high volume manufacturing (HVM) test solution based on Intel® SVT architecture. With this test solution, the test points are placed on the JTAG pins of the processor and PCH and other required signals, and the Intel enabled test tool will make contact to the test point pads on the secondary side of the board via dual end probes. The figure below illustrates the typical setup of the Intel enabled DFM HVM test solution.

Figure 46-23. Intel DFM HVM Test Solution High Level View



Besides routing test point pads to JTAGs and PROC_PREQ# and PROC_PRDY#, CFG[3], SPIO_IO2 signals of processor and PCH as outlined in [Section 46.1.1](#), Several others signals must also be routed to test point pads. these signals are:

- **PowerGood (HOOK0)** - Route RSMRST# to a test point pad to use as HOOK0 signal.
- **RESET_N (HOOK6)** - Route ITP_PMODE to a test point pad as HOOK6 signal for both processor and PCH.
- **DBR# (HOOK7)** - Route SYS_RESET# to a test point pad as HOOK7 signal.
- **Power (VccOBS_AB) and Ground (GND) Pins** - Route PCH_V1.0A Rail or equivalent voltage rail to a test point pad as the VccOBS_AB pin and route two ground (GND) pins directly to a GND plane through individual vias.

There is no trace length limitation on these signals, but it is recommended to optimize when routing between each signal to its test point pad and keep trace length to minimum whenever possible.

To reduce the GND affect and improve signal integrity, the following are recommended for supporting the manufacturing testing of the motherboard:



- Test point pads must be used on the secondary side of the motherboard for tester accessibility via pogo pins.
- Prefer pad size is 25 mil, but 18 mil is acceptable. The pad size must meet the industry standard for boundary scan test.
- The pads are not required to be arranged into a particular pad pattern. However, TCK signals must be routed with GND pads nearby.

46.1.8 Depopulation Guidelines for Debug Port

At some point there may be a desire to remove the debug port from the board especially when the debug is no longer needed. It is recommended that the debug-port real estate and pads remain in place if they need to be populated for a future problem.

Coffee Lake has adequate internal bias resistance on JTAG, PROC_PREQ# and PROC_PRDY# signals to keep the devices in an idle state without the external pull up resistors.

It is acceptable to replace the standard resistor values with any resistor value between $51\ \Omega$ to $3k\ \Omega$ to reduce bill-of-material items when the debug is no longer needed.

Processor BPM#[3:0] nets can be left floated when not use for debug. Processor CFG[19:0] and PCH chipset test interfaces might have dual purpose usage. From XDP debug perspective, external components (resistor, jumper, or FET switch) between XDP connector and chipset test interfaces can be removed when debug is no longer needed; however, there might be a need to keep the strap resistor and the external components in place for the non debug usage of the interfaces; for example the "OR" gates associated with the VCCST/VCCSTG XDP Power Override Mechanism in Figure 44-4.

Refer other relevant chapters in Platform Design Guide (PDG), External Design Specifications (EDS) and your Intel representative for addition information on these signals.

From XDP perspective, it is fine to remove the isolation resistors of HOOK pins on the XDP side of the routing when debug is no longer needed. Refer relevant sections in PDG, EDS and your Intel representative before removing the external pull up resistor that tie to XDP HOOK pins.

Note:

Intel recommends at least route the JTAG signals according to [Section 46.1.3](#) on the production board to support closed chassis debug after production.

§ §



47

Platform Thermal Management Design Guidelines

Thermal management consists of a way to sense temperature and a means of reducing the temperature if it is above a specified limit. For each major component of the platform, thermal management is available for the user to implement into their system design to ensure sufficient platform cooling.

Table 47-1. Platform Thermal Management Reference Documents

Title	Location
Coffee Lake Client Platform Thermal Management Design Guide	571296

47.1 Platform Thermal Management Signal Descriptions

47.1.1 Signal Groups

The following signals must be connected for proper Intel® Turbo Boost Technology and overall platform thermal management behavior.

Table 47-2. Signal Groups

Signal ⁴ Name	Routing Guideline	Description
PECI	Connect PECI directly from EC to the processor	PECI allows EC read / write access to registers to control thermal management
PROCHOT# ¹		
AC_PRESENT#		Senses whether AC is present on the platform
ADAPTER_ICC ²	Connect from System Charger to EC	Senses Icc for the power adapter. Allow EC to monitor total platform power.
BRICK_ID ³	Connect from AC Adapter to EC	Detect power limit for the AC Adapter

Notes:

1. Platform needs to enable bi-directional PROCHOT# through Processor MSRs.
2. The GPIO on EC should be capable of A/D conversion.
3. Implementation of this signal is optional.
4. All Signals: Refer [Section 14.2.7, "Platform Environmental Control Interface \(PECI\) Topology"](#), and [Table 14-4](#).

47.2 Platform Thermal Management Configuration, Connectivity, Block Diagram

Intel recommends that the system EC owns all platform thermal management buses and events. All platform components report their temperature to the EC so that platform software can provide an appropriate response. EC connects to the processor using PECI signal (EC is PECI Host). EC that supports PECI 3.0 is capable of getting per core or full processor package temperature data during turbo operation and also



temperatures in low power Cstates. EC connects to PCH through SMLink1 which can be used to report the direct PCH DTS temperature. Other platform thermal sensors can be connected to the EC directly through the SMBus.

Figure 47-1. Thermal Management Option 1

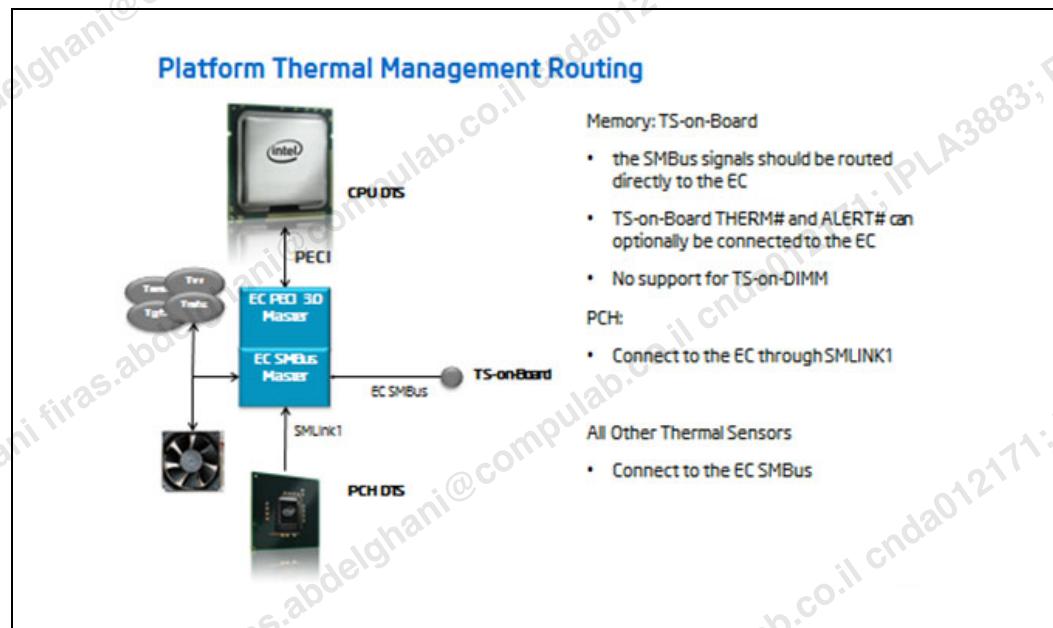
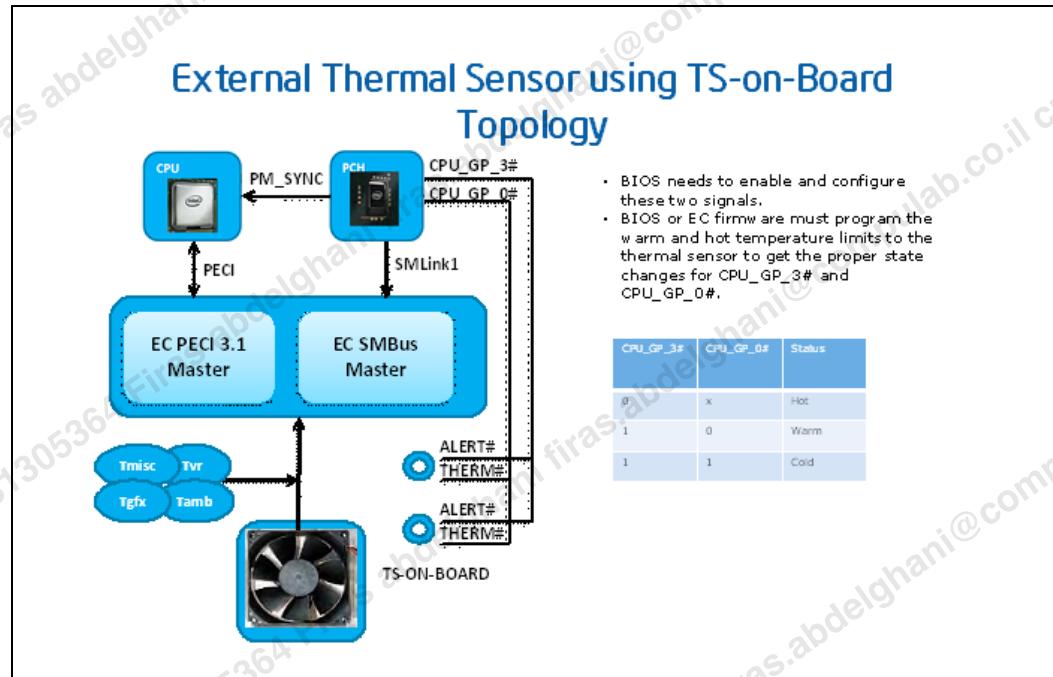


Figure 47-2. Thermal Management Option 2



§ §

48 Acoustic Noise Mitigation

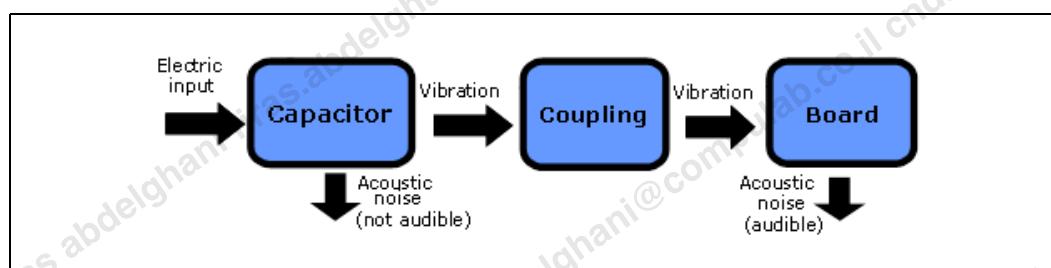
48.1 Introduction

Audible acoustic noise can be generated by electronic components, such as capacitors or inductors, when they vibrate due to large, fast and periodic voltage or current changes. Since platform power management techniques (e.g., processor C-state management) can cause such voltage transitions, it is important to address and minimize the acoustic risk.

These vibrations are transferred through the rigid mounting of the electronic components to the board. Multi-layered ceramic capacitors (MLCC) are most prone to this, because they are of rigid construction and rigidly mounted to the board. The circuit board acts as a sounding board, and audible acoustic noise is radiated.

This acoustic noise generation scenario is demonstrated in [Figure 48-1](#). In such a scenario, there are a few architectural design guidelines that should be followed in order to minimize the risk of generating audible acoustic noise.

Figure 48-1. Flow Chart of Acoustic Noise Generation



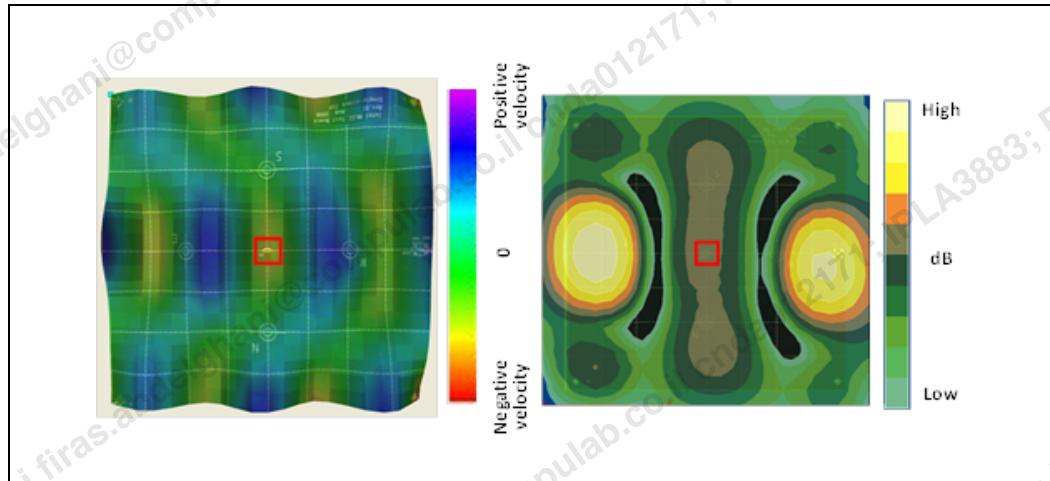
To illustrate some of the complexity involved, the vibration pattern generated by a single capacitor when mounted in the center of an otherwise unpopulated board is shown in [Figure 48-2](#).

The left-hand pattern shows “peak” and “valley” deflections throughout the board. The right-hand pattern shows the acoustic response generated by the board vibrations due to the capacitor vibration.

In this example, the acoustic maxima are symmetrically located on the left side and the right side of the board, because that is the orientation of the mounting pads that transmit the vibration. That the acoustic maxima locations do not correspond to the vibration source (i.e. capacitor) creates an added complexity for troubleshooting the acoustic issue. Therefore, it is not advised to use microphone scanning to identify the vibrating source component.

Figure 48-2. Example Vibration (Left) and Acoustic Radiation (Right) Pattern Generated by One Capacitor Mounted in the Center of Test Board

Note: Capacitor Location Denoted by Red Square



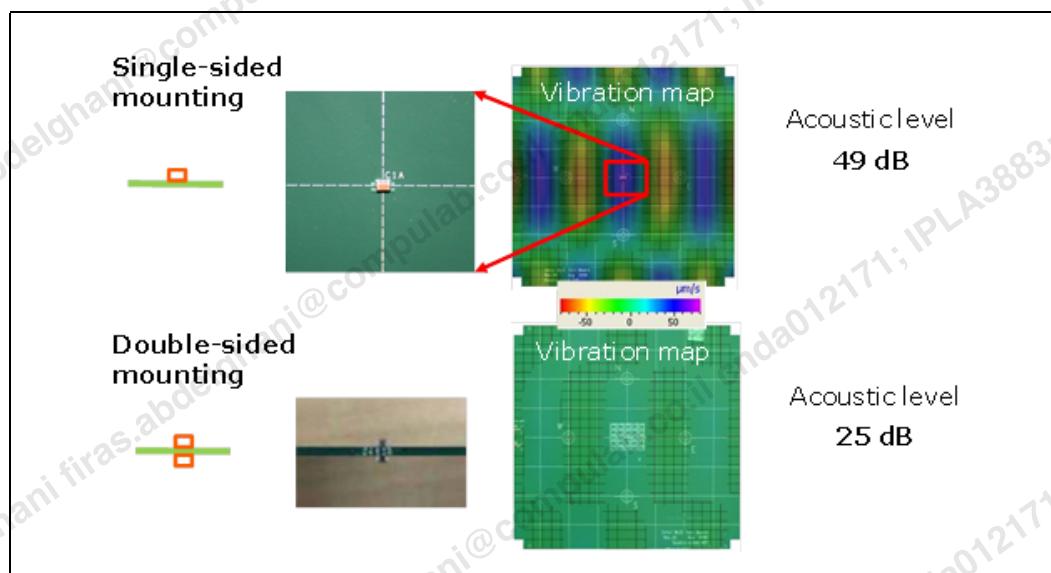
48.2 Noise Mitigation

48.2.1 Mechanical Mitigation

It is good mechanical design practice, if board layout and space allows, mounting capacitors that are driven by the same electrical signal on both sides of the board directly opposite each other. This symmetrical mounting cancels out a large part of the vibrations generated by the capacitors, and therefore the acoustic noise. An example of this is shown in [Figure 48-3](#), where two capacitors with symmetric mounting generate a significantly lower acoustic level than a single-sided mounted capacitor. The example is an idealized test case, and the amount of reduction seen in a real system might be less.

Figure 48-3. Example: Single-sided Mounted Capacitor Generates 49 dB Sound Pressure Level (SPL) while Symmetrically Mounted Capacitor Generate 25 dB

Note: SPL Measured Just Above Capacitor



Even though mechanical precautions have been taken, acoustic noise at lower levels can still be generated. Therefore, architectural guidelines also need to be adhered to for minimizing the acoustic noise.

48.2.2 Architectural Mitigation

48.2.2.1 Signal Parameters

The acoustic noise generated depends upon the voltage swing and frequency of the voltage changes. The acoustic noise decreases with decreasing voltage swing. However, reducing the voltage swing could have a negative effect on the potential power savings. In addition, the frequency of the voltage swing is a parameter to consider in reducing the perceived impact of the acoustic noise. The audible frequency range is 20 Hz - 20 kHz, and this frequency range is divided into three different regions (low, mid and high) in this text. It is acoustically beneficial to employ specific frequencies for periodic processor interrupts in each of these three regions as described below.

1. Low frequency (20 Hz - 200 Hz) range; the extreme ends of this range are recommended for reducing the perceived noise. The 70 Hz frequency is technically the worst to use, due to the human perception of this frequency (called roughness). However, the acoustic noise level is lower for interrupts across this range, and therefore generally not noticed.
2. Mid frequency (200 Hz - 1 kHz) range; 200 Hz - 300 Hz is preferred.
3. High frequency (1 kHz - 20 kHz) range; higher frequency is preferred to reduce the number of harmonics in the audible range. If there is a need to operate at lower frequencies in this range, it should be done with caution. The human ear is most sensitive in the frequency range of 1 - 6 kHz. Hence, interrupt frequencies in this range, especially 1 kHz, should be avoided if possible.



Another parameter to consider is the ramp rate of the voltage changes. The ramp rate is defined as the voltage change over unit time and describes how fast and/or slow electronic components experience voltage level changes. Different ramp rates can impact the strength of the harmonics; however, there is an interaction with the duty cycle of the transition. Therefore, different ramp rates must be tested on a case-by-case basis for their acoustic benefit.

48.2.2.2 Software and Settings

BIOS/UEFI settings should be used to synchronize the EHCI controllers, and USB selective suspend should be enabled, because these settings can reduce the likelihood of voltage or current changes that may trigger acoustic noise. Refer to BIOS Writers Guide for details.

48.2.2.3 Dynamic Periodicity Alteration

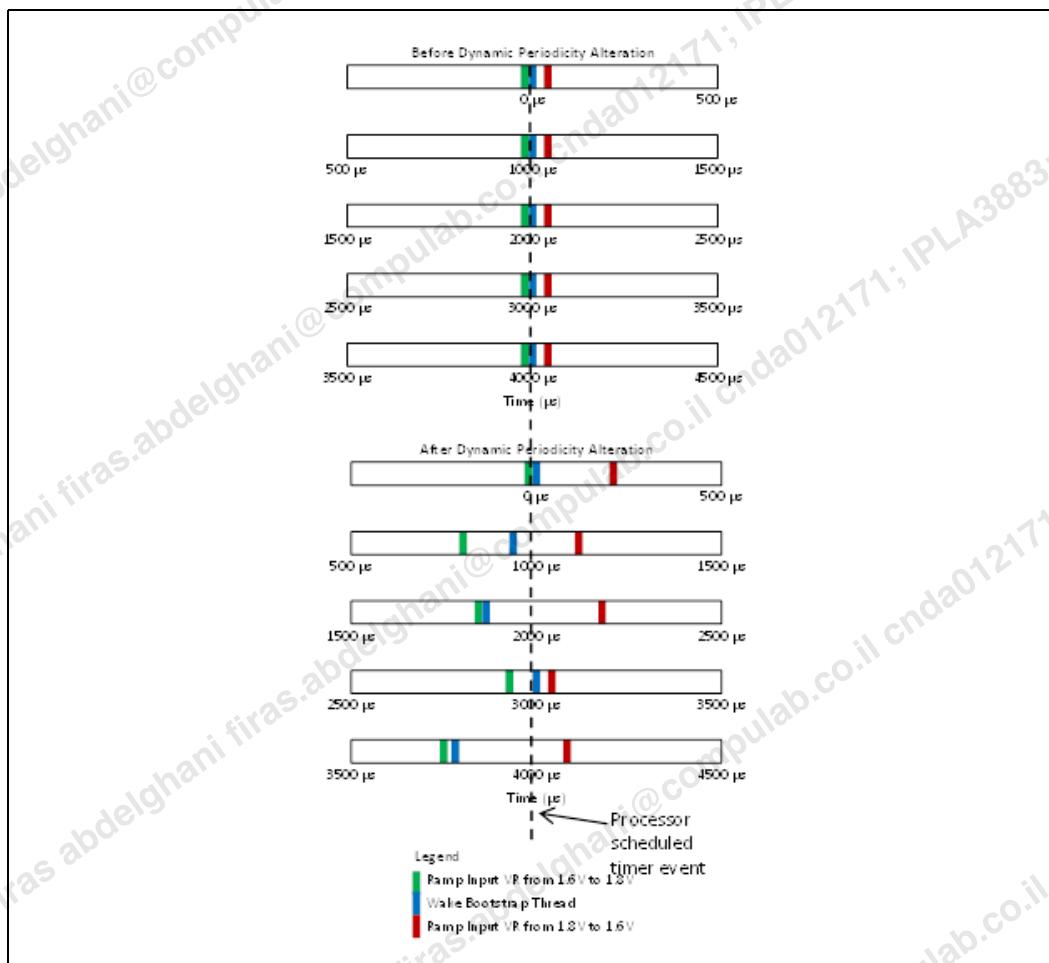
An architectural mitigation methodology that addresses the acoustic issue directly at the source by disrupting/altering the periodicity of the electrical signal is called Dynamic Periodicity Alteration (DPA). A requirement for audible acoustic noise is periodic voltage/current transitions. The most common scenario when such transitions occur is during an Operating System (OS) or application-scheduled timer event. When there are no applications to execute in the near future, the CPU enters into a sleep state (C-state). When the timer expires, an interrupt occurs and wakes the CPU from the sleep state. This sleep-wake sequence can result in periodic voltage transitions that can cause audible noise. By disrupting the periodicity, the acoustic levels can be reduced and can become less audible to the user.

Without a DPA implementation, the processor pursues a “just-in-time” wake-up strategy. This involves ramping the input VR and waking a core just before the timer event expires. Immediately after the timer event is serviced, the processor ramps the input VR back down to the lower voltage. The result is high power efficiency, but periodic timer ticks result in periodic power actions and the potential for unacceptable acoustic noise.

The DPA implementation pseudo-randomizes the scheduling of these three power actions: ramping the input VR from 1.6V to 1.8V (first introduced on 4th Generation Intel® Core™ Processor), waking the bootstrap thread (essentially waking a core), and then ramping the input VR down from 1.8V to 1.6V. BIOS can program the maximum range of the randomization of each event. For each event, a different pseudo-random number is chosen to alter the timing of these three actions.

Figure 48-4 shows a pictorial representation of the resulting behavior. The diagram depicts time advancing from top to bottom and left to right, with each segment representing a 1 ms time interval. The left side of the diagram shows an example of what the behavior is without DPA. A timer tick at a 1 ms interval causes the three power actions (ramp input VR from 1.6V to 1.8V, wake a core, and ramp input VR from 1.8V to 1.6V) to occur at regular intervals. The diagram shows how these power actions align between subsequent time intervals. The diagram on the right shows the result of the architectural mitigation of periodic power events with DPA. The regular interval between power events is disrupted by the introduction of pseudo-randomness in the scheduling of power actions. The amount of time off-set is adjustable.

Figure 48-4. Before (Top) and After (Bottom) the Implementation of Dynamic Periodicity Alteration



It is up to the OEM to set the appropriate randomization ranges depending upon the severity of the acoustic noise generated. If the OEM needs to enable the DPA feature, two features should be employed before employing the full three-feature DPA. The two features to activate first are either pre-wake or ramp-up, which should be combined with ramp-down. The OEM should start with a low randomization range and increase the range until the acoustic noise is mitigated. The range is between 0 (no DPA) to the maximum value of max 255 us [0xff]. This staged approach will ensure the lowest power penalty of the DPA feature. If the noise is still not mitigated, the full three-feature DPA should be employed (pre-wake, ramp-up, and ramp-down), and the OEM should again start with a low randomization range and increase the range until the noise is mitigated.

Refer the appropriate BIOS Writers Guide for details of register settings and implementations.



48.2.2.4 Constant Voltage Regulator (VR) Voltage

If periodic excitations are not due to scheduled timer events, DPA does not apply. In this case, the recommendation is to keep C-states enabled, but reducing the min VID so there is either no or a reduced voltage delta between the sleep states. This approach can also be used in conjunction with or in place of DPA even for timer driven events, if further acoustic mitigation is required. Refer CPU dependent VR guidelines for details.

§ §

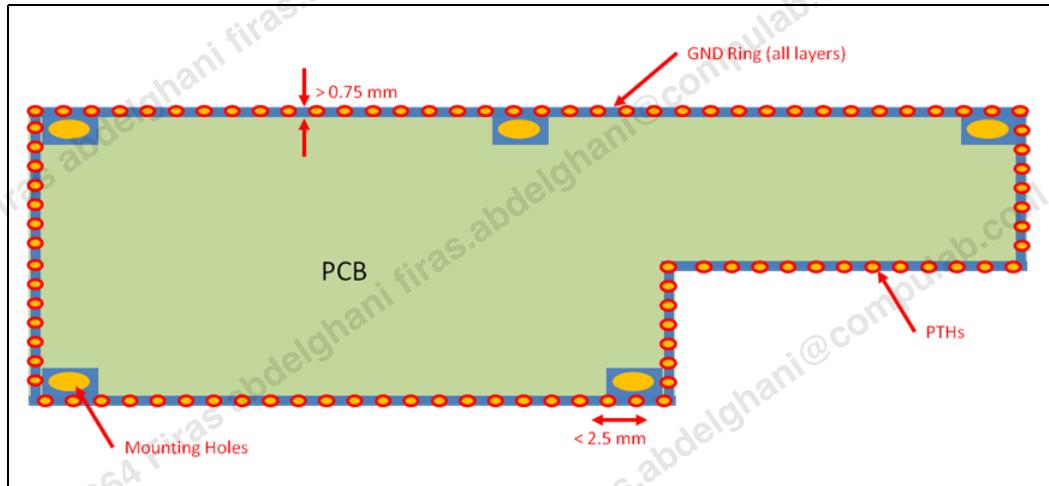
49 Electromagnetic Compatibility

49.1 General Considerations

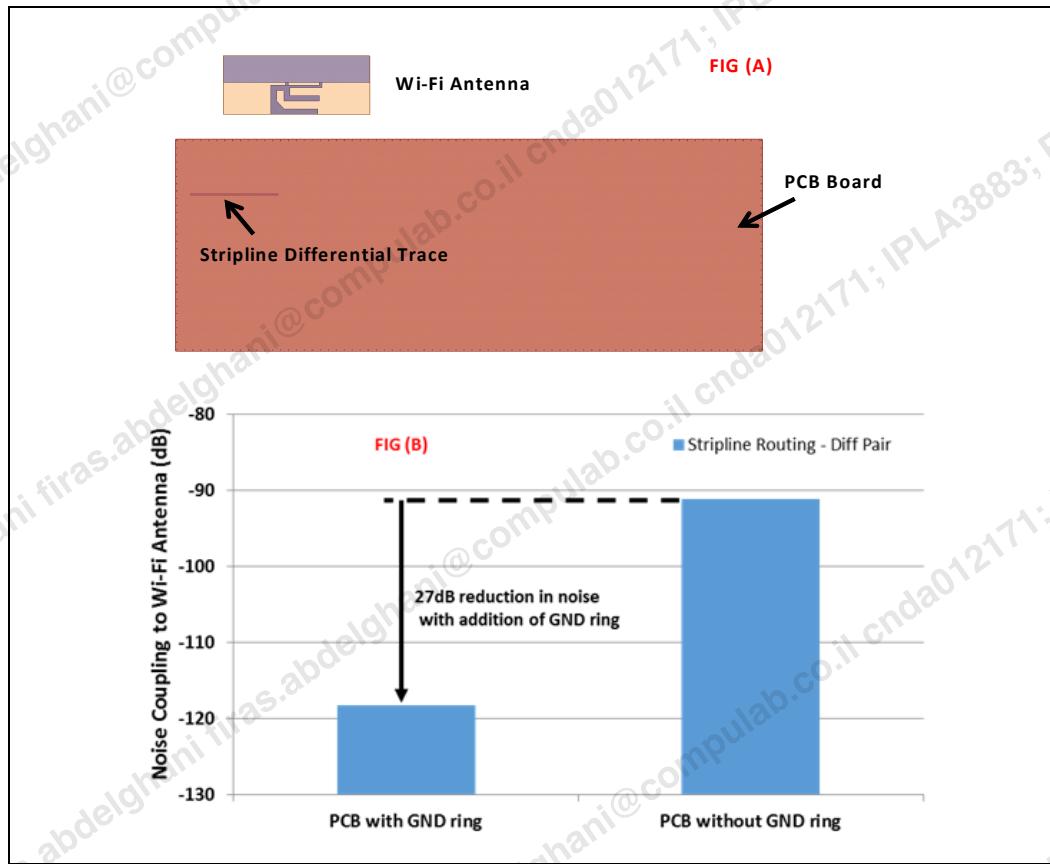
49.1.1 Ground Ring/ PTH

- Ground rings on all layers and ground PTHs are recommended on the edge of the board.
- Ground ring should be a continuous and solid shape with no splits and minimum shape neck width is 0.75mils.
- At least 0.5mm gap between ground ring and other signal traces/shapes.
- The ground shape should connect to multiple mounting holes electrically. This connects the PCB ground to chassis ground. The mounting holes need to be evenly distributed.
- The ground shape is useless without proper vertical stitching to the ground layer. Connector holes can be considered stitching vias. Add vias throughout the length of the ground shape, no more than 2.5mm apart, close to the board's edge. Refer figure below.

Figure 49-1. Ground Ring/ PTH

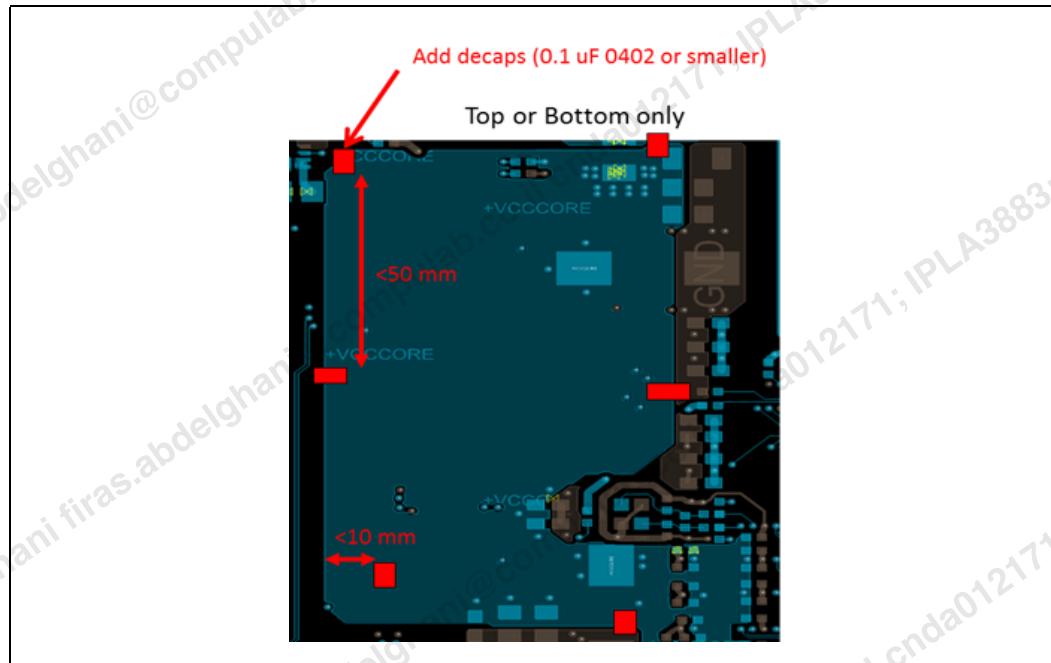


The following example shows the impact of adding the ground ring. Below figure (FIG (A)) shows a PCB board with a differential trace routed as stripline. The trace length routed was 50mm. A Wi-Fi Antenna is included in the model and is placed 50 mm away from the differential trace. The differential trace is excited with a common mode signal. The impact of the ground ring is assessed by comparing the noise coupled to the antenna with and without a ground ring in use. Below figure (FIG (B)) shows the noise coupling comparison with and without the ground ring. The noise coupling can reduce by 27dB when a ground ring is used.

Figure 49-2. Example - Ground ring

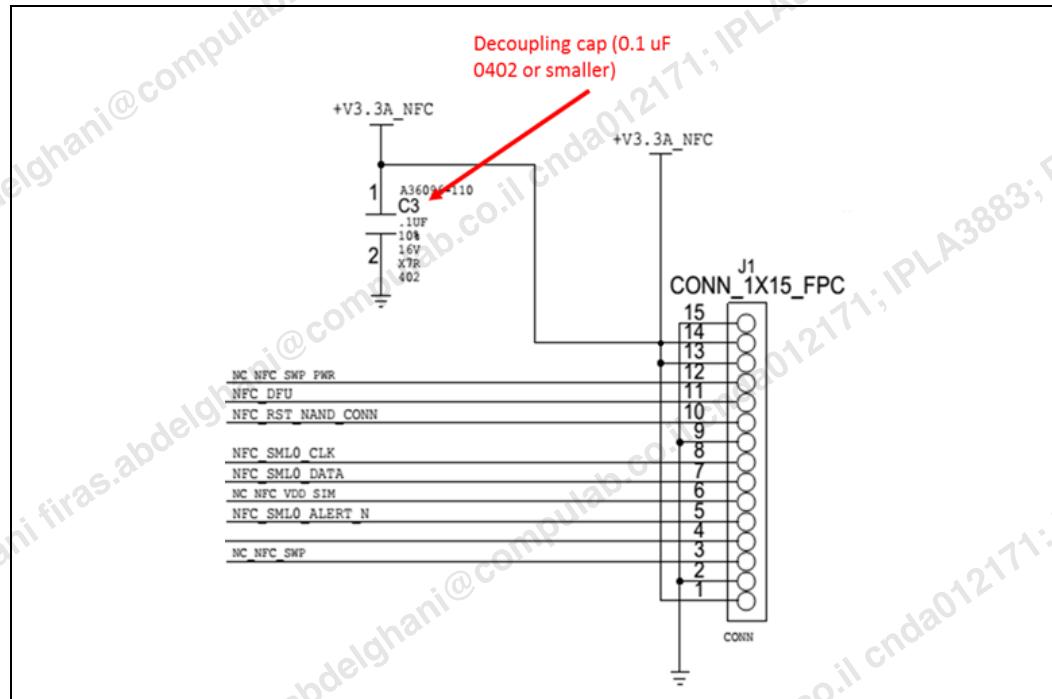
49.1.2 Power Plane Decoupling

Power planes on top and bottom layers longer than 50 mm may have significant emission. Decoupling capacitors (0.1 uF, 0402 or smaller) need to be placed along the edge of such power plane with spacing <50 mm. The decoupling capacitors need to be within 10 mm from the edge of power planes. Decoupling may be skipped when there already existing similar capacitors (0.1 uF, 0402 or smaller) within 10 mm. Refer figure below.

Figure 49-3. Power Plane Decoupling

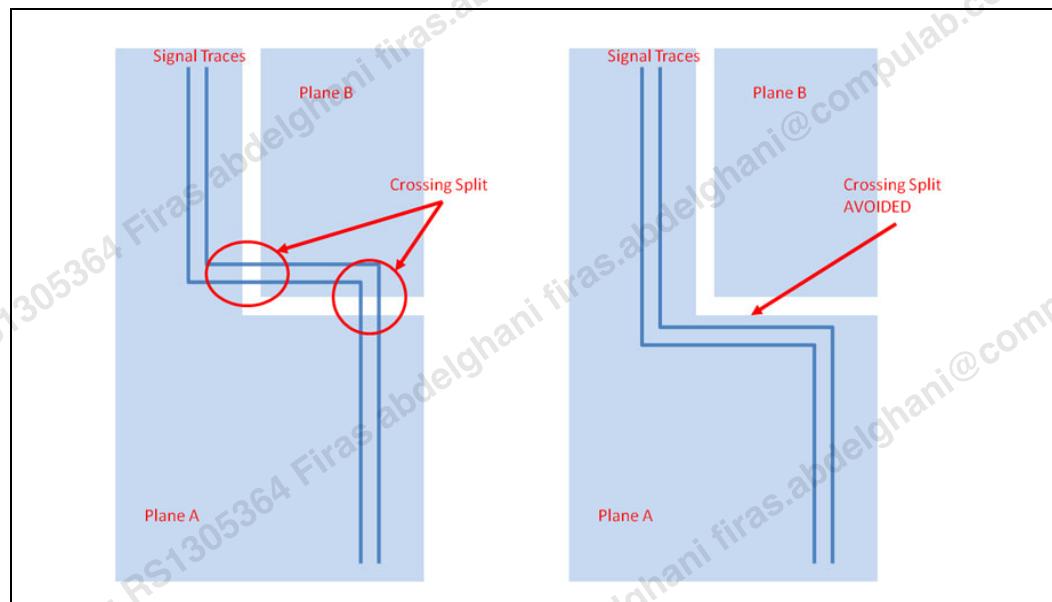
49.1.3 Connector Decoupling

Decoupling capacitor placed on power pins of internal and external connectors to reduce the noise on power rails and recommended capacitor value is 0.1uF 0402 or smaller. Refer figure below for example.

Figure 49-4. Example for Connector Decoupling

49.1.4 Crossing Split planes

Crossing split planes increases the emissions from the signal traces. Recommended to avoid crossing split planes by moving the traces or reshape the power planes. Refer figure below for example.

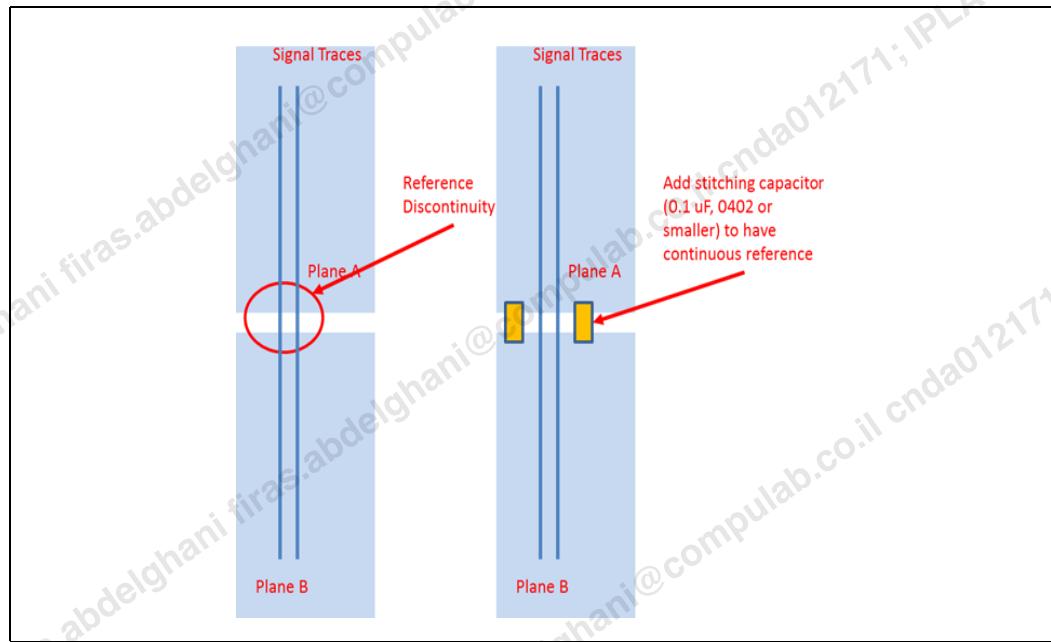
Figure 49-5. Example for Traces Crossing Planes

49.1.5

Reference Discontinuity

- Changing reference plane from GND to power plane, or from power plane A to power plane B, may significantly increase noise emission.
- It is recommended to have stitching capacitors (0.1 uF, 0402 or smaller) to bridge the two reference planes and provide current return path. Refer figure below for stitching capacitors placement.

Figure 49-6. Stitching Capacitors Placement

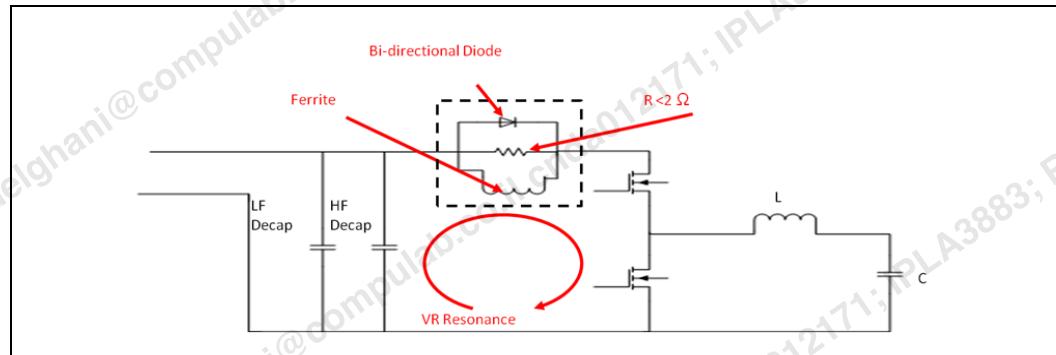
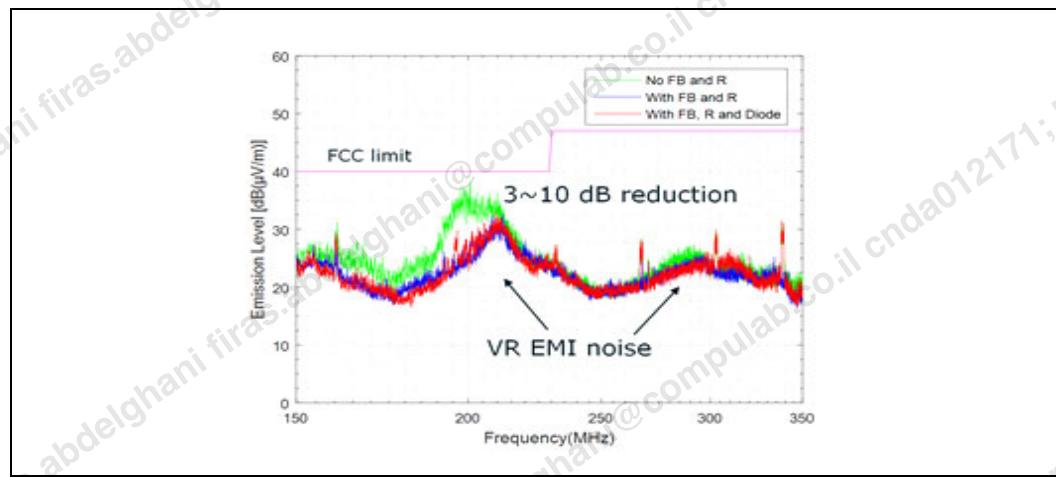


49.2 Power Supply

49.2.1

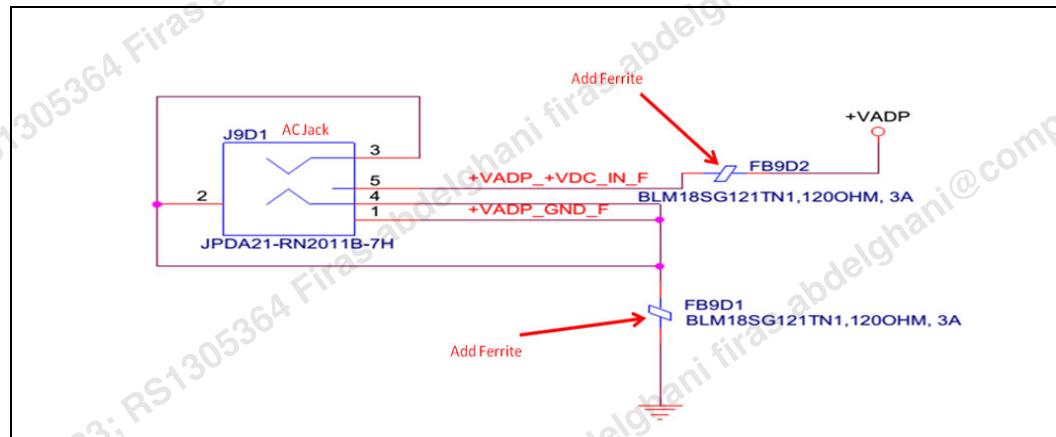
Voltage Regulator

- Switching mode regulators (including battery charger) have EMI/RFI noise caused by parasitic resonance.
- A filter at voltage input may reduce the noise. The filter consists of a ferrite bead, diode and a resistor.
- The selection of the components depends on the VR design. An example of ferrite bead BLM18SG121TN1, diode ESD300-B1-02LRH, and 2-ohm resistor shows 3-10 dB EMI reduction in 3-m chamber. It is recommended resistor to be no larger than 2 ohm. Refer figure below for input filtering circuit.
- Place the decoupling capacitors very close to the top transistor. The ground pin of the capacitors should be connected to the solid ground plane right underneath.
- Use at least two decoupling capacitors to reduce overall parasitic inductance from the capacitors themselves.
- Have a solid ground plane immediately underneath the VRM circuit and connect the VRM ground to the solid ground plane through vias.

Figure 49-7. VRM Input Filter**Figure 49-8. Measurement Results**

49.2.2 AC Jack

Ferrite Bead on both power and GND pins of the AC jack to reduce EMI emissions. Refer figure below.

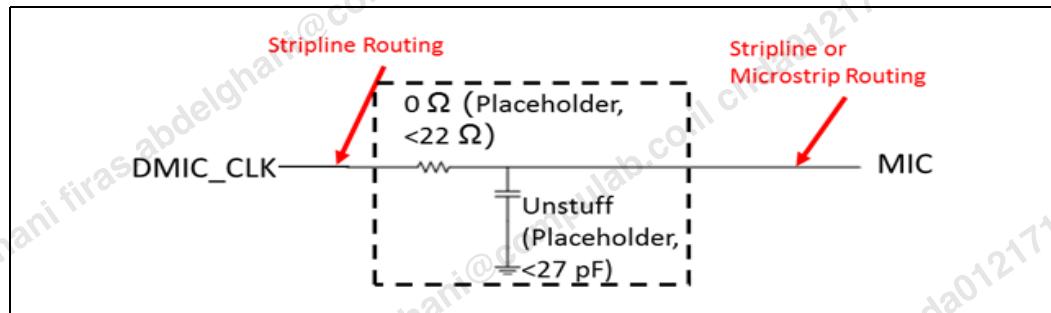
Figure 49-9. Filtering Circuit for AC Jack

49.3 Critical Signals

49.3.1 Audio

- DMIC clock may have EMI/RFI risk due to its high-order harmonics.
- Recommend to have strip line routing and a RC filter before being routed in microstrip/cable to reduce high-frequency harmonics.
- The RC value may vary according to the board design. Refer figure below.

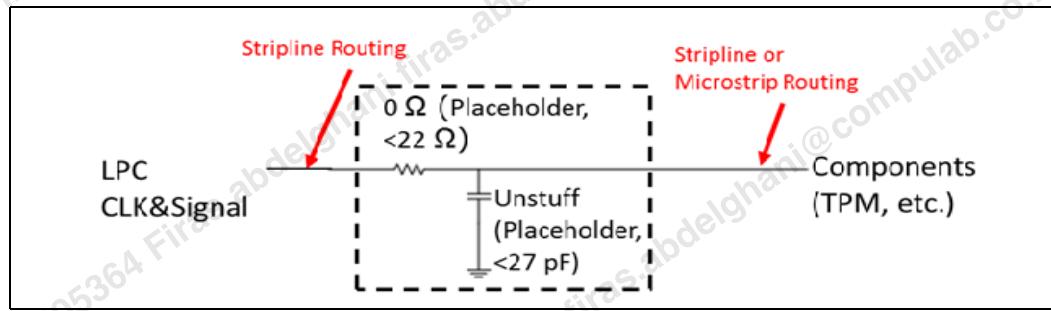
Figure 49-10.Filter for DMIC_CLK



49.3.2 LPC

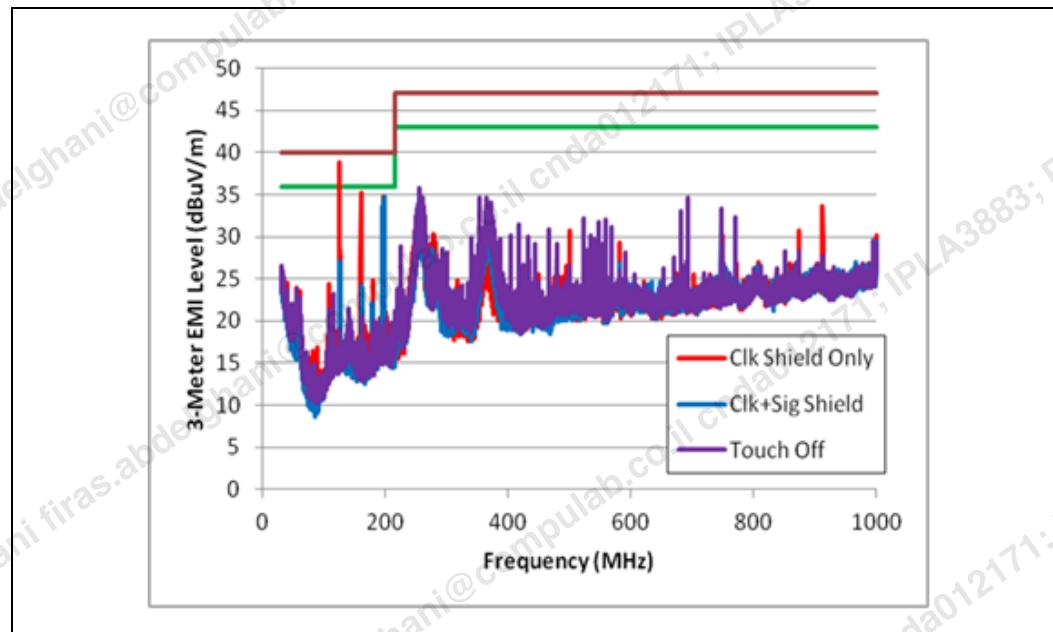
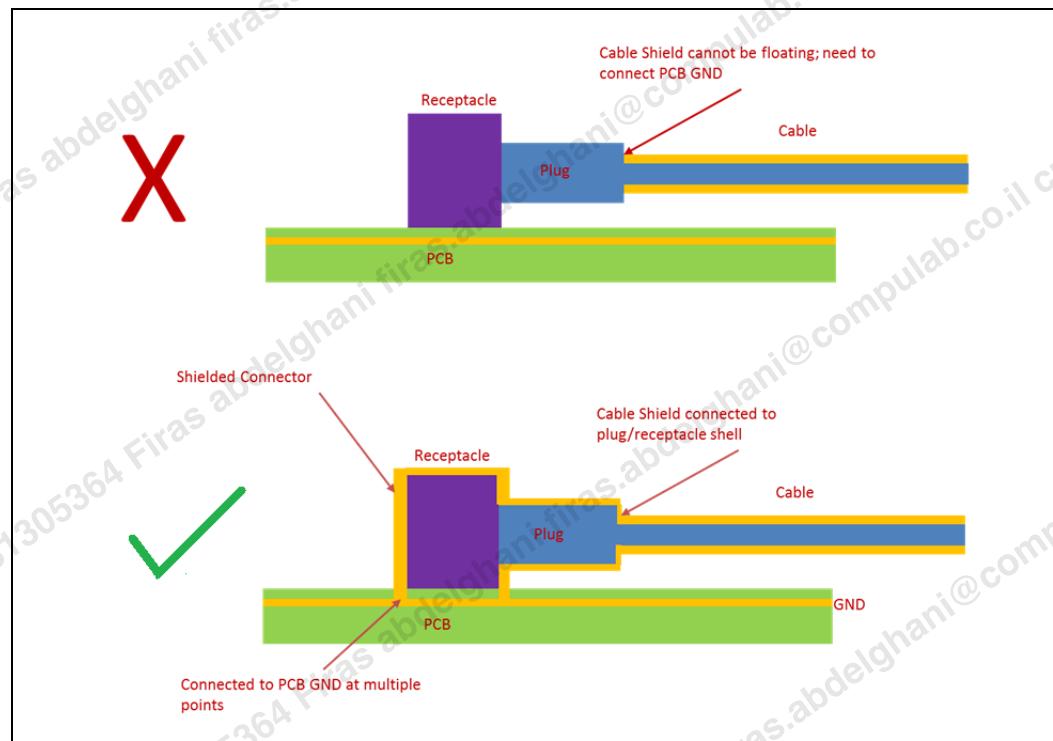
- LPC clock and signals may have EMI/RFI risk due to its high-order harmonics.
- Recommend to have stripline routing and a RC filter before being routed in microstrip/cable to reduce high-frequency harmonics.
- The RC value may vary according to the board design. Refer figure below.

Figure 49-11.Filter for LPC_CLK



49.3.3 Integrated Touch (SPI)

- The SPI interface used in integrated touch may have EMI concerns.
- Recommend to use shielded cable for both clock and signal. Refer figure below for noise comparison.

Figure 49-12.Noise Comparison - With Shield and Without Shield**Figure 49-13.SPI Cable Shielding**

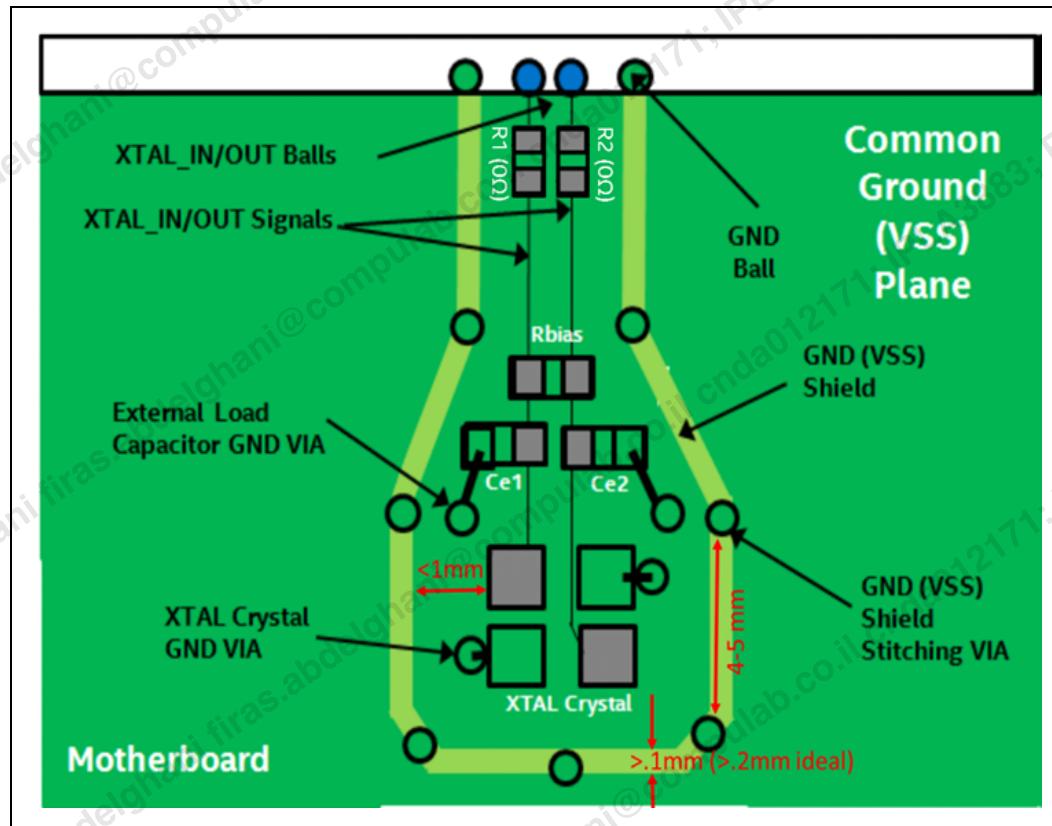
49.3.4 Crystal (Xtal) RF Immunity

- The 24 MHz crystal that provides the input clock to the PCH Integrated Clock Controller has been identified to be very sensitive to RF power from nearby radios.
- Radiated power from internal WWAN and WLAN antennas as well as from external WWAN devices placed near the platform can couple to the crystal and corrupt the clock signal causing issues such as screen flickering and system hang.
- Similarly the crystal used with the Thunderbolt Interface Controller is very sensitive to RF power and noise from nearby antennas can result in connection loss with the device plugged into the Thunderbolt port.
- Refer to Thunderbolt design collateral for xtal spec and recommended xtal part. (Document #563553)

The following RF Immunity Guideline applies to both the 24MHz crystal as well as the Thunderbolt/retimer crystal.

49.3.4.1 RF Immunity Guidelines

- For 24MHz nssc differential clock: Ideally, for RF immunity, the traces between PCH and CPU should be covered by GND plane.
- Ensure that external HSIO (SATA, USB3.1, DP) and internal HSIO (PCIe) traces are not routed in close proximity to the crystal components and traces (XTAL_IN/OUT)
- Follow crystal routing guidelines very carefully. (Refer to Platform Clock Design Guidelines section)
- Add a series 0-Ohm resistor stuffing option on XTAL_IN and XTAL_OUT traces as a reserved option for possible debug and mitigation to unintended RF power effects, refer to below figure. Intel has only done limited validation of mitigation options and recommends customers to do additional testing.
- Add a ground ring surrounding crystal part, related components and routing may help to reduce the EMI risk. Refer to below figure. Do not connect external load caps to GND ring, but rather directly to GND plane on adjacent layer.
- Use a shielded crystal component.
- Place crystal far away from antennas and potential RF power coupling paths such as unshielded/ungrounded cables. Exact distance needed depends on platform design.
- Platforms without board shield have higher risk.
- WWAN antennas pose higher risk than WLAN antennas because of WWAN's higher transmit power.

Figure 49-14. 0-Ohm Series Resistors for Crystal Signals

49.3.5 EMC Sensitive Nets

The following nets may be sensitive to ESD injection based on measurement on KBL platform. Similar trends are expected on CFL platform.

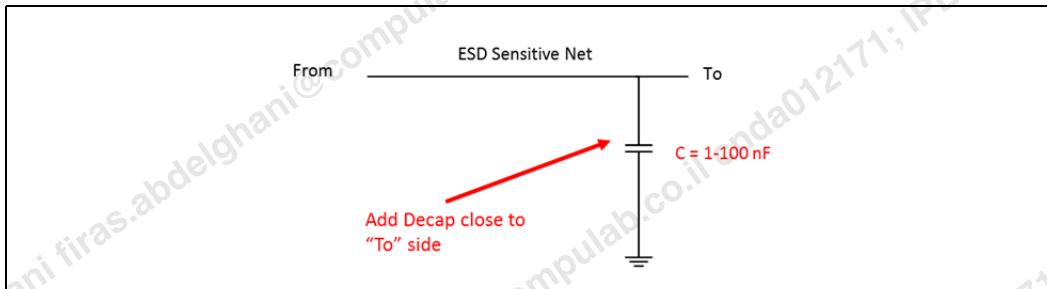
Table 49-1. Sensitive Nets

Net Name
PROCHOT_N
XTAL_IN
XTAL_OUT
VCCST_PWRGD
GPP_E_9_USB2_OCB_0
VCCAPLLEBB
VCCDUSB_1PO
VCCAPLL_1PO
DRAM_RESETB
VCCDTS_1PO

System-level ESD issue may be mitigated by,

- Routing sensitive nets as stripline.
- Adding decoupling capacitors on the sensitive nets to reduce the ESD level injected into the victim ICs (excluding crystal oscillator). The value of capacitor varies on different nets and systems. The recommended value is 1-100 nF. Refer figure below.

Figure 49-15. De-coupling Capacitor for Sensitive Net



- Follow specific guideline of crystal layout (Refer to document #564413).

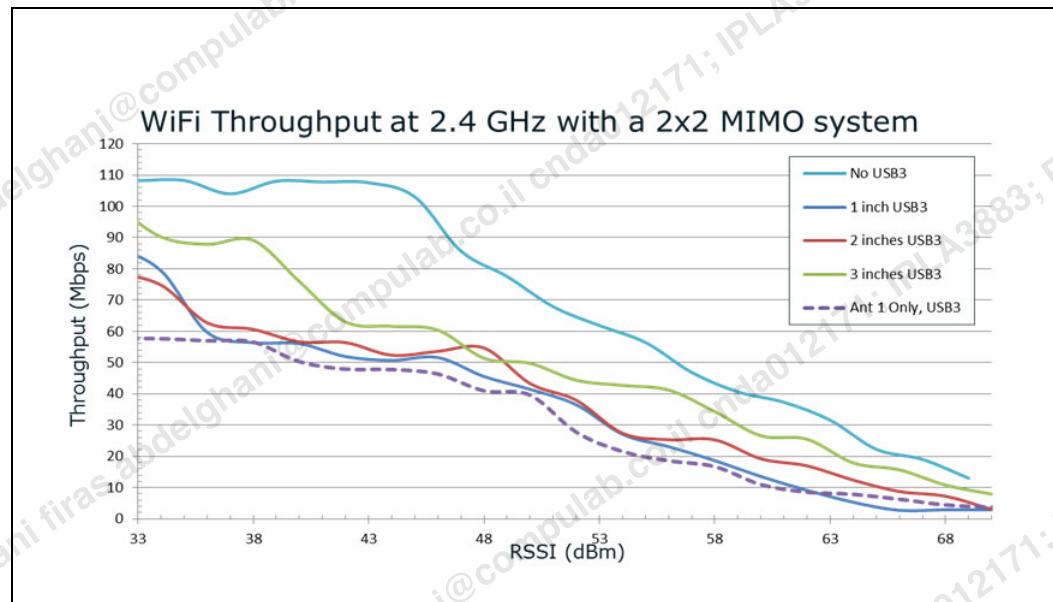
49.4 Connectors

49.4.1 General Guidelines

- Proper ground shielding for the connector can reduce the radiation.
- Proper contact to the chassis of host platform can reduce the radiation.
- Recommend to have multiple ground points between receptacle and plug.

49.4.2 USB

- Radio antennas (Wi-Fi, WWAN, GNSS, etc) need to be placed away from USB3.1 type-A connector to avoid radio-frequency interference (RFI).
- Wi-Fi antennas need to be at least 3" away to avoid significant Wi-Fi performance degradation.

Figure 49-16.Measurement Results

49.4.2.1 USB Type-C Connector Considerations

Following are the recommendations for Type C receptacle connector selection.

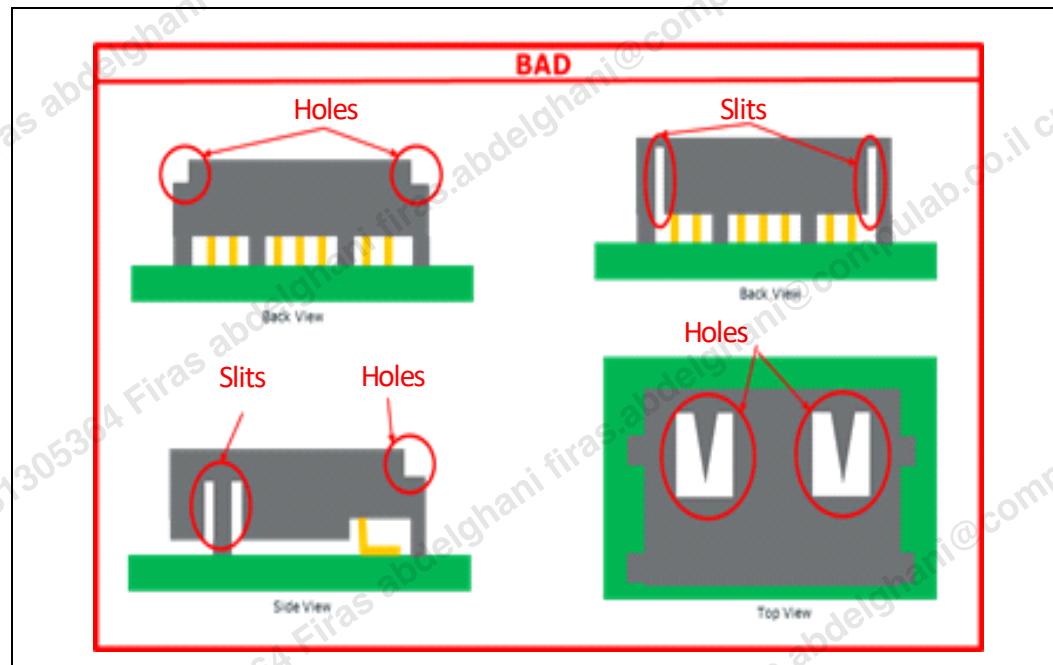
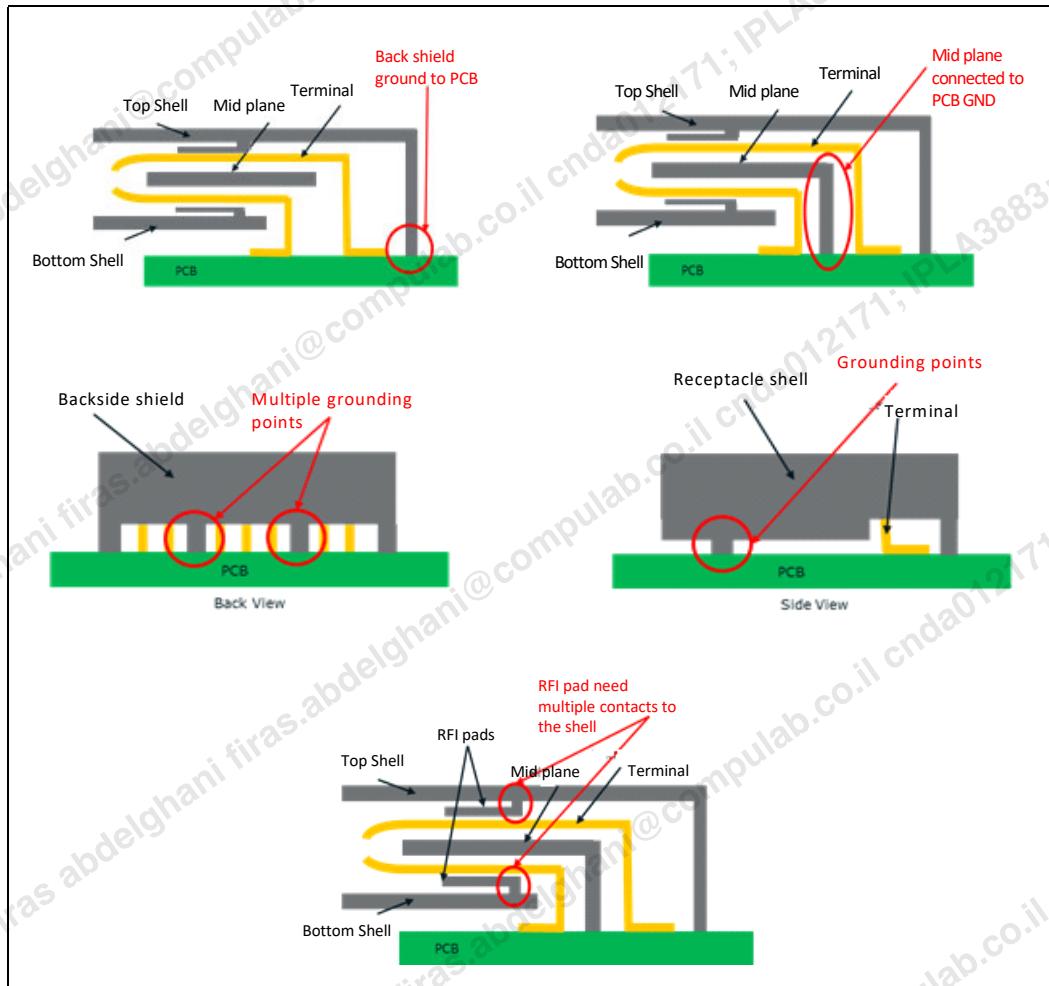
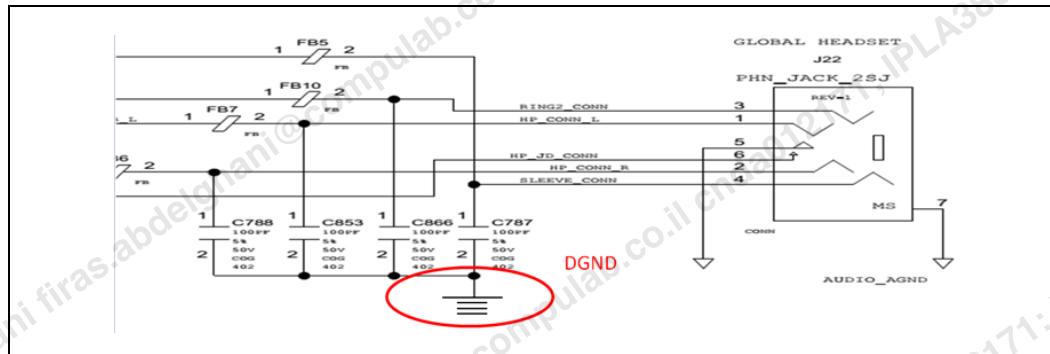
Figure 49-17.Improper Shielding for USB Connectors

Figure 49-18.Poor Shielding For Connectors

Figure 49-19.USB3 Type-A Connector Shielding


49.4.3 Audio Jack

- Audio jack needs to have EMI/ESD protections composed of ferrite beads and decoupling capacitors.
- The decoupling capacitors need to connect the digital/chassis ground. Refer figure below.

Figure 49-20.Filter Circuit for Audio Jack

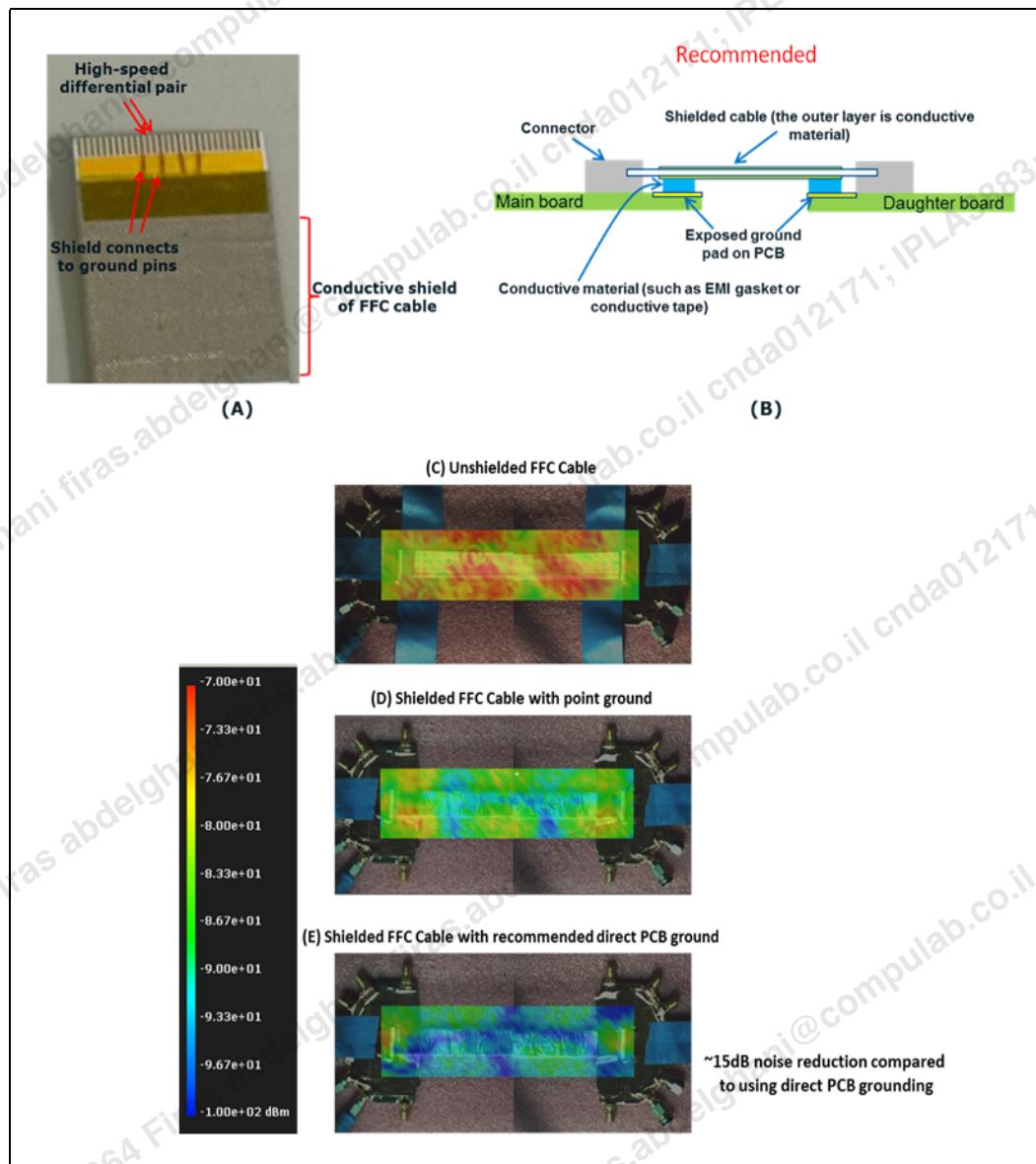


49.5 Cables/ Shielding

49.5.1 Shielded FFC

- Internal Cables are frequently used to carry high speed signals such as USB3, eDP, MIPI CSI etc. Noise from such high speed interfaces can radiate and cause EMI, RFI issues.
- A shielded FFC cable may be used as an alternate to expensive three-layer FPC cables. The method by which the shield layers of a flexible cable are contacted to ground has a significant impact on the RFI performance and noise reduction.
- In order to make the shielding effective, the shield layer cannot be floating. A floating shield does not provide a return current path and may even make the noise radiation worse.
- When the shield ground connection is through the ground pins as in below figure (A) the return path inductance could still be high when compared to the PCB ground connection. This results in higher noise radiation.
- To improve the ground contact of the shield, a direct PCB connection of the shield, shown in below figure (B) is recommended. Using conductive tape or an EMI gasket, the shield of the cable is made to directly contact a ground pad on the PCB.
- The near-field scanning plots in below figure (C), (D) and (E) show the comparison of the RFI from an unshielded cable, shielded FFC with ground pin connection and shielded FFC with the recommended direct PCB ground contact.
- As can be seen in below figure (E), the RFI is significantly reduced even half inch away from the cable.

Figure 49-21. Shielded FFC Cable Design Recommendations



49.6 PCB CMC Technology

- To provide a low-cost alternative to using discrete CMCs, Intel has developed a PCB embedded common-mode filter solution to mitigate radio frequency interference (RFI). Compared to conventional discrete CMC solutions, the PCB-CMC only consumes slightly larger PCB space but without the extra cost.
- PCB-CMC technology is designed specifically for RFI mitigation, and it can be applied to high speed differential data interfaces such as USB 3.1, eDP, and HDMI.



- For access to Intel PCB-CMC technology, a legal agreement is required. To proceed or check status of License/Evaluation Agreement with Intel for the PCB-CMC Technology, please contact your Intel field representative. For the latest and most complete information on PCB-CMC technology refer to the Intel White Paper# 546122.

Figure 49-22.PCB CMC

	4-layer PCB-CMC	6-layer PCB-CMC	6-layer-X PCB-CMC 5mm	6-layer-X PCB-CMC 3mm
Layout				
Stack-ups supported	Type 3 & 4; 4-layer	Type 3 & 4; 6,8&10-layer	Type 3 & 4; 6,8&10-layer	Type 3 & 4; 6,8&10-layer
Typical application	Desktop, AIO, daughter card	Notebook, Ultrabook, tablet	Notebook, Ultrabook, tablet	Notebook, Ultrabook, tablet
Signal speed supported	Up to ~5 Gbps	Up to ~5 Gbps	Up to ~10 Gbps	Up to ~10 Gbps
RFI mitigation	WLAN, WWAN	WLAN 2.4GHz, WWAN	WLAN, WWAN	WLAN
Common-mode filter BW	1.8GHz – 6GHz	1.8GHz – 3.7GHz	1.8GHz – 6GHz	2.4-2.5GHz & 5-6GHz
Differential Insertion Loss	-3dB @ 7.5GHz	-3dB @ 7.5GHz	-3dB @ 10GHz	-3dB @ 10GHz

49.7 Components Selection

Below components are used for internal reference design. Intel does not recommend a specific part/device or circuit because each solution is board/chassis/usage model specific. Customers should choose the components on their own based on the recommended components specifications. Refer below tables for some examples of CMC and ESD components for different interfaces.

Note:

Due to routing limitations, full stripline routing may not be possible. Recommend <25.4mm microstrip routing at break-out region and <25.4 mm microstrip routing at connector region to reduce EMI/RFI risk.

Table 49-2. Examples for CMC Components Selection (Sheet 1 of 2)

Interface	Routing	Cable	Placement	Cutoff Frequency (3-dB Band width)	Insertion Loss	CM Rejection (10-dB Band)	Reference part
USB 2.0	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	-	<0.2 dB @240 MHz	0.5-2.0 GHz	DLW21SN900SQ2L ACM2012-900-2P-T002
USB 3.1 Gen1	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	>7.5 GHz	<1.5 dB @2.5 GHz	1.8-3.8 GHz	PCB CMC: MCF0605G120
USB 3.1 Gen2	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	>10 GHz	<1.2 dB @ 5 GHz	1.8-3.8 GHz	PCB CMC: NFP0QHB372HS2

**Table 49-2. Examples for CMC Components Selection (Sheet 2 of 2)**

Interface	Routing	Cable	Placement	Cutoff Frequency (3-dB Band width)	Insertion Loss	CM Rejection (10-dB Band)	Reference part
HDMI	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	>6 GHz	<0.8 dB @1.5 GHz <1.3 dB @3 GHz	0.3-3.8 GHz	DLP11SA900HL2
DP	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	>10 GHz	<1.2 dB @ 5 GHz	1.8-3.8 GHz	PCB CMC NFP0QHB372HS2
eDP	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	>10 GHz	<1.2 dB @ 5 GHz	1.8-3.8 GHz	PCB CMC NFP0QHB372HS2
SATA	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	>7.5 GHz	<1.5 dB @ 5 GHz	1.8-3.8 GHz	PCB CMC MCF06052G120

Table 49-3. Filter requirements for other interfaces

Interface	Routing	Cable Shielding	Placement
SPI	Stripline	Shielded FPC/FFC/Coax	Placeholder for shunt capacitor
DMIC	Stripline	-	22 Ω + 27 pF (Placeholder)

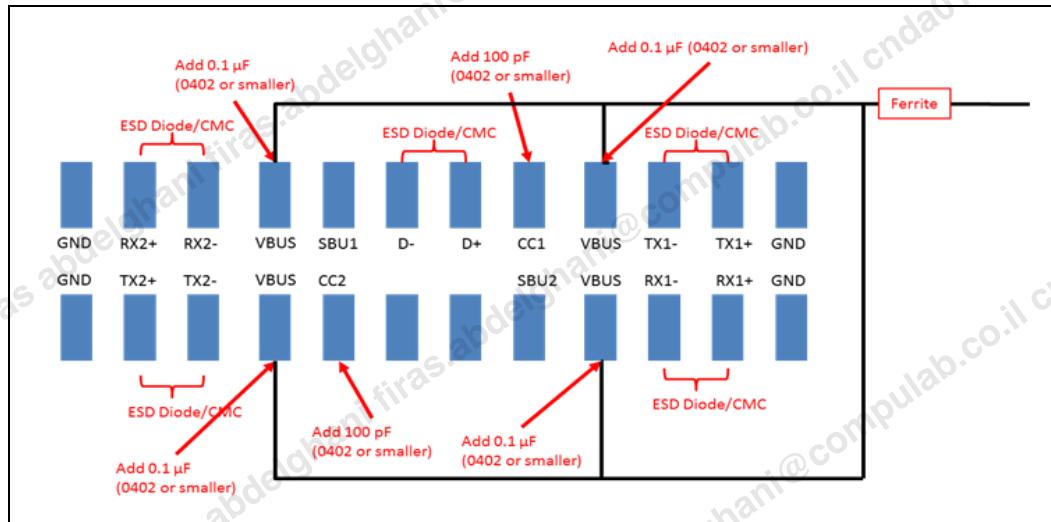
Table 49-4. Examples for ESD Components Selection

Interface	Routing	Cable	Placement	Shunt Capacitance	Rdyn	Reverse working voltage	Reference part
USB 2.0	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	<1.5 pF	<0.8 Ohm	<6 V	ESD105-B1-02ELS CM1230
USB 3.1 Gen1	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	<0.5 pF	<0.5 Ohm	<6 V	ESD102-U4-05L
USB 3.1 Gen2	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	<0.35 pF	<0.5 Ohm	<6 V	PUSB3FR4
HDMI	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	<0.4 pF	<0.5 Ohm	<6 V	ESD102-U4-05L
DP	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	<0.4 pF	<0.5 Ohm	<6 V	ESD102-U4-05L
SD CARD	Stripline	Shielded FPC/FFC/Coax	<25.4mm from connector	<0.4 pF	<0.5 Ohm	<6 V	ESD102-U4-05L
Thunderbolt	Stripline	-	<25.4mm from connector	<0.35 pF	<0.5 Ohm	<6V	PESD5V0H1B

Table 49-5. Other Critical Decoupling Capacitors and EMI Filtering Components

Interface	Component Requirement	Recommended Part Number/ Part Value
AC JACK	Ferrite Bead on power and ground pins of AC JACK	BLM18SG121TN1
Voltage Regulator	EMI filter at the voltage input (ferrite, diode, resistor)	Refer Section 49.2
XTAL	Series 0-ohm resistors	Refer Section 49.3.4
VCC_IN, VCC_AUX	Decoupling caps	Refer Chapter 50
Type C Connector	Decoupling caps on VBUS signal pins (x4) Decoupling capacitor on CC1 and CC2 pins	0.1uF 100pF
	Ferrite Bead on VBUS	refer below section, TYPE C EMI and ESD consideration

49.7.1 Type C EMI and ESD Components

Figure 49-23.Type C ESD Protection

For CMC placement on Type C signals, refer below table according to the usage scenario.

Table 49-6. TYPE C CMC guidelines

Port Usage	CMC Guideline
USB3 Only	Place Tx CMCs and Rx CMCs are optional
USB3 and DP	Place both Tx and Rx CMCs due to emission from DP
USB3 and TBT	Do not place either Tx and Rx CMCs



§ §



50 Processor and PCH Power Integrity Recommendations

This chapter details the decoupling and layout recommendations for the processor and PCH.

Table 50-1. Reference Documents

Title	Document Number / Location
Coffee Lake Platform Device Power Targets and Related Recommendations	571086
Coffee Lake Turbo and Thermal Power Management Guide for Intel® Core™-based Processors	571040

50.1 Processor Decoupling and Layout Recommendations

Follow processor decoupling capacitor requirements in the following table to ensure component maintains stable supply voltage. The capacitors should be placed as close to the package as possible (100 mils or 2.54 mm nominal) in a location that would effectively decouple the interfaces listed under 'Domain'. All decoupling capacitors need to have at least X5R rating. Intel recommends including pads for extra power plane decoupling capacitors for prototype board designs.

The decoupling requirements in this document are based on a 150-kHz Unity Gain-Bandwidth VR. As a rule of thumb, the assumption of Unity Gain-Bandwidth of a VR is $1/4^{\text{th}}$ of the switching frequency (F_{sw}). In this case, we're using 600-kHz as the switching frequency in our simulation and the requirements here are based on these assumptions. As for decoupling in CRB reference design, these are based on 150-kHz Unity Gain-Bandwidth VR and hence, the difference in decoupling requirements.

XTAL signals are sensitive to noise. If the XTAL is placed near a noisy power plane and the signal lines are routed without proper isolation, the noise can be coupled from the power planes to the signals and cause issues.

50.1.1 Coffee Lake H Processor Layout Recommendation

In order to prevent manufacturing yield loss (open solder joint defects), the surface layer under the package cavity should be voided. This is to avoid package land side capacitors interacting with the board surface model inside package cavity area and ensure SMT yield.

The copper shape and plane inside the cavity are required to be removed. Ideally, PTHs/vias and pads inside the cavity should be avoided. The cavity keepout zone recommendation is shown below.

To account for manufacturing process variations, the optimal design will maintain a distance of 150um from any PTH/via to the package landside capacitors (as measured from the via edge to LSC body outline) inside the cavity.

In the case that PTHs/vias has to be placed inside the cavity area, it is recommended to place them strategically to avoid overlapping with package landside capacitors. Clp/dxf files for landside capacitor locations are also provided in the collateral RDC#572464 Coffee Lake Package Landside Capacitor dxf and clp files, which can be imported into the CAD tool to aid the design.

Figure 50-1. CFL H 6+2 CPU Cavity Keep Out Zone Recommendation

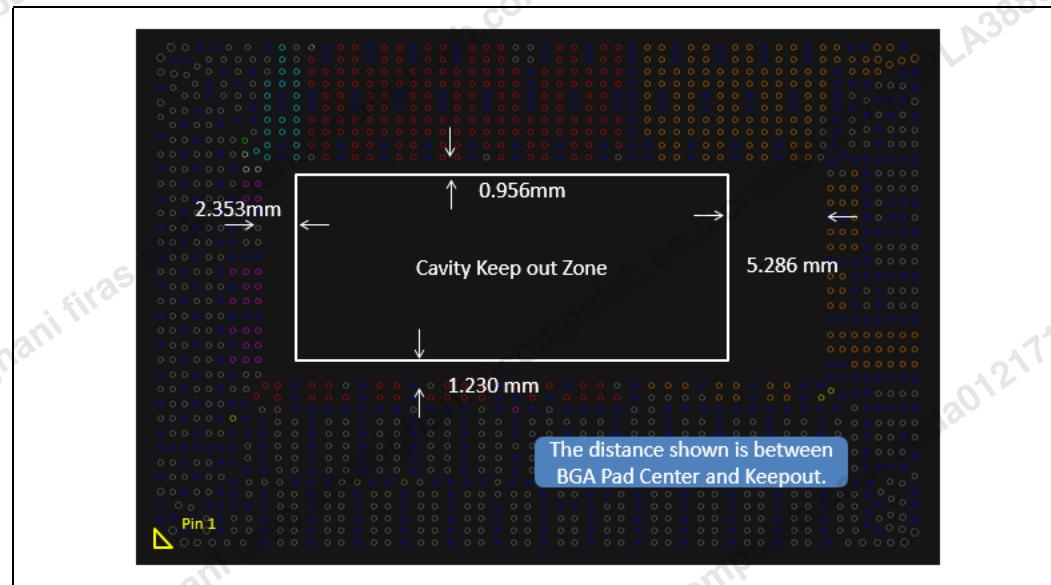
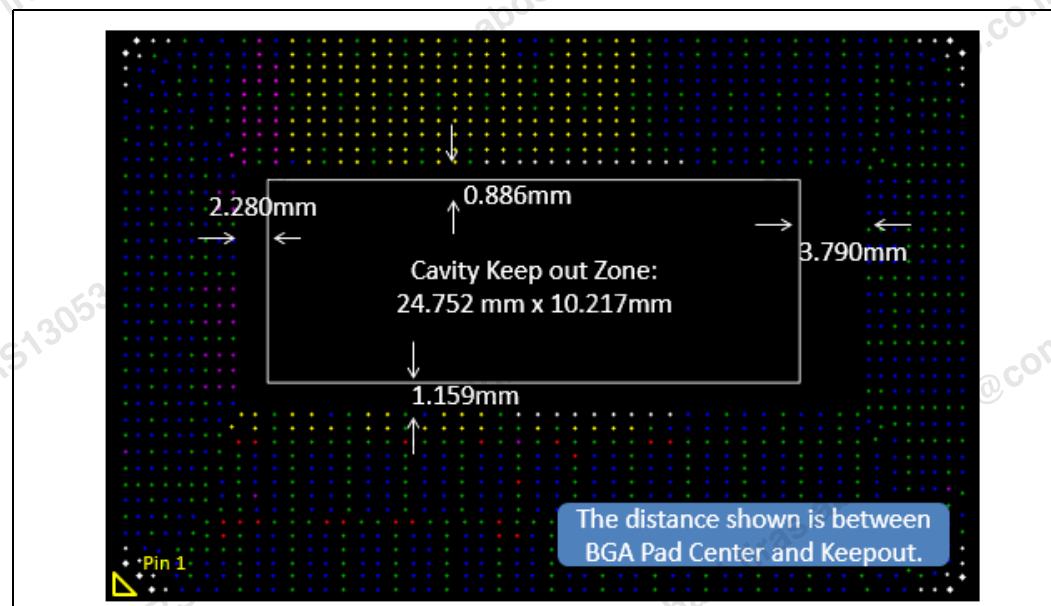


Figure 50-2. CFL H 8+2 Refresh CPU Cavity Keep Out Zone Recommendation





50.1.2 Coffee Lake Decoupling Requirement

Table 50-2. CFL H 6+2 Bulk Decoupling Example

Bulk Decoupling Locations	EXAMPLE	Notes
Vcc Power Plane at VR output	3x 330uF	Place on top of board, near processor edge
Vcc _{GT} Power Plane at VR output	2x 220uF	Place on top of board, near processor edge
Vcc _{IO} Power Plane at VR output	2x 47uF 0805	Place close to VR output
Vcc _{SA} Power Plane at VR output	2x 47uF 0805	Place on top of board, near processor edge

Note: 220uF aluminium polymer bulk cap listed above should have ESR @ 5m ohm and ESL @ 1.9nH each. These are the values used in power distribution simulations used by Intel. They are not vendor specifications.

Table 50-3. Decoupling Requirements for CFL H 6+2 Processor (Sheet 1 of 2)

Domain	Board Edge cap	Backside cap	Notes
Vcc	5x 47uF 0805		
		12x 22uF 0603	
		21x 10uF 0402	
		24x 1uF 0201/0402	
		24x 0201/0402 (placeholder)	
Vcc _{GT}	3x 47uF 0805		Place as close to the BGA as possible
	7x 22uF 0603		
		10x 10uF 0402	
		12x 1uF 0201/0402	
Vcc _{SA}	2x 47uF 0805		
	2x 22uF 0603		
		7x 10uF 0402	
		1x 1uF 0201/0402	
V _{DDQ}		4x 22uF 0603	
		11x 10uF 0402	
Vcc _{IO}		3x 10uF 0402	Additional capacitors might be needed if the connectivity from BGAs to capacitors is not adequate.
		3x 0402 (placeholder)	
Vcc _{ST}		1x 1uF 0201/0402	Must be Ground referenced. Board routing resistance from BGA to Power gate should be less than 10mOhm. Do not route Vcc _{ST} closest adjacent layer over any power net other than ground.
Vcc _{STG}		1x 1uF 0201/0402	Must be Ground referenced. Share with 1.0V PCH rail

**Table 50-3. Decoupling Requirements for CFL H 6+2 Processor (Sheet 2 of 2)**

Domain	Board Edge cap	Backside cap	Notes
V _{CCPLL}		1x 1uF 0201/0402	Must be Ground referenced. Share with 1.0V PCH rail. Board resistance from BGA to Power gate should be less than 130mOhm.
		1x 22uF/47uF 0805 (placeholder)	*Placeholder not stuffed. To be placed as close as possible to BGA (H28, J28) and be placed either at board edge or backside.
V _{CCPLL_OC}		2x 1uF 0201/0402	Must be Ground referenced. Share with V _{DDQ} . Board resistance from BGA to Power gate should be less than 86mOhm.
Note: High Current Rail assuming 600KHz for VR bandwidth. Higher VR bandwidth assumptions results in lower quantity of MLCC (0805/0603) to meet the same AC loadline. Note: It is important to make sure that the noise on V _{CCPLL} rail must be limited to the +/-5% VR specification below 150KHz - as this will potentially impact the PLL failing to phase lock. Where necessary, the 0805 placeholder can be stuffed with a 22uF or 47uF to assist noise reduction. While stuffing the 0805 cap may reduce noise coupling, one should still route the PLL rail carefully (i.e. to avoid noisy and high current rail) to mitigate any potential issue.			

Table 50-4. CFL H 8+2 Bulk Decoupling Example

Bulk Decoupling Locations	EXAMPLE	Notes
V _{CC} Power Plane at VR output	2x 220uF 7343	Place on top of board, near processor edge
	2x 220uF 7343	Place on the backside.
V _{CCGT} Power Plane at VR output	2x 220uF	Place on top of board, near processor edge
V _{CCI0} Power Plane at VR output	2x 47uF 0805	Place close to VR output
V _{CCSA} Power Plane at VR output	2x 47uF 0805	Place on top of board, near processor edge

Note: 220uF aluminium polymer bulk cap listed above should have ESR @ 5m ohm and ESL @ 1.9nH each. These are the values used in power distribution simulations used by Intel. They are not vendor specifications.

Table 50-5. Decoupling Requirements for CFL H 8+2 Processor (Sheet 1 of 2)

Domain	Board Edge cap	Backside cap	Notes
V _{CC}	2x 22uF 0603		
	8x 47uF 0805		
		48x 1uF 0201/0402	
		42x 10uF 0402	
		10x 22uF 0603	
V _{CCGT}	3x 47uF 0805		Place as close to the BGA as possible
	7x 22uF 0603		
		10x 10uF 0402	
		12x 1uF 0201/0402	

**Table 50-5. Decoupling Requirements for CFL H 8+2 Processor (Sheet 2 of 2)**

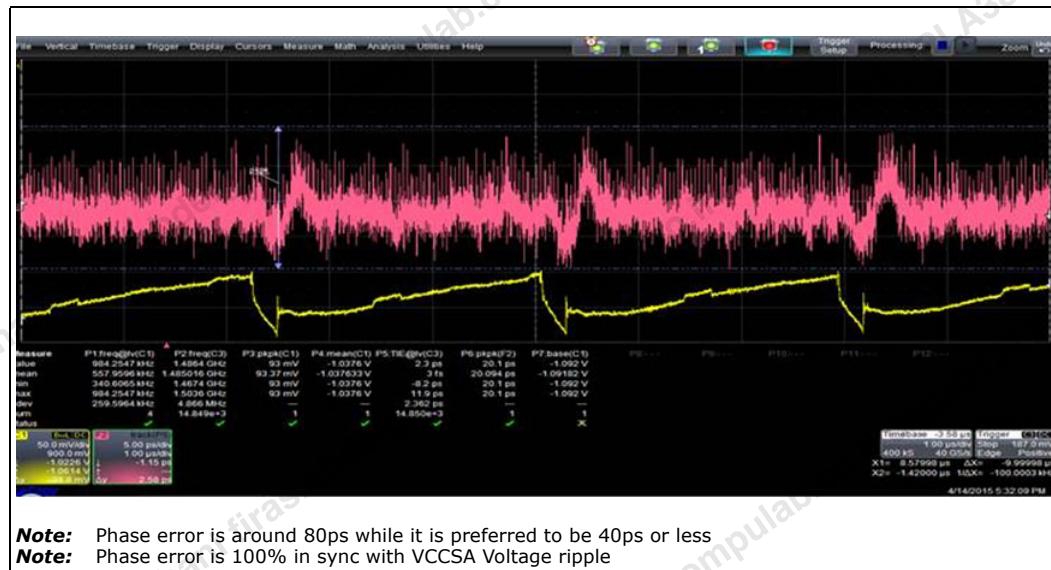
Domain	Board Edge cap	Backside cap	Notes
V _{CC_{SA}}	2x 47uF 0805		
	2x 22uF 0603		
		7x 10uF 0402	
		1x 1uF 0201/0402	
V _{DDQ}		4x 22uF 0603	
		11x 10uF 0402	
V _{CC_{IO}}		3x 10uF 0402	Additional capacitors might be needed if the connectivity from BGAs to capacitors is not adequate.
		3x 0402 (placeholder)	
V _{CC_{ST}}		1x 1uF 0201/0402	Must be Ground referenced. Board routing resistance from BGA to Power gate should be less than 10mOhm. Do not route V _{CC_{ST}} closest adjacent layer over any power net other than ground.
V _{CC_{STG}}		1x 1uF 0201/0402	Must be Ground referenced. Share with 1.0V PCH rail
V _{CC_{PLL}}		1x 1uF 0201/0402	Must be Ground referenced. Share with 1.0V PCH rail. Board resistance from BGA to Power gate should be less than 130mOhm.
	1x 22uF/47uF 0805 (placeholder)		*Placeholder not stuffed. To be placed as close as possible to BGA (H28, J28) and be placed either at board edge or backside.
V _{CC_{PLL_}OC}		2x 1uF 0201/0402	Must be Ground referenced. Share with V _{DDQ} . Board resistance from BGA to Power gate should be less than 86mOhm.
Note: High Current Rail assuming 600KHz for VR bandwidth. Higher VR bandwidth assumptions results in lower quantity of MLCC (0805/0603) to meet the same AC loadline. Note: It is important to make sure that the noise on VCCPLL rail must be limited to the +/-5% VR specification below 150KHz - as this will potentially impact the PLL failing to phase lock. Where necessary, the 0805 placeholder can be stuffed with a 22uF or 47uF to assist noise reduction. While stuffing the 0805 cap may reduce noise coupling, one should still route the PLL rail carefully (i.e. to avoid noisy and high current rail) to mitigate any potential issue.			

50.1.3 VCCST PLL Jitter Recommendation

VCCST PLL jitter issue was found during Intel internal validation and it was causing by power rail overlapping between VCCSA/VCCST on RVP.

Figure 50-3 below shows the example of PLL jitter from VCCSA/VCCST overlapping on RVP.

Figure 50-3. VCCSA Ripple (Yellow) vs PLL Phase Error (TIE)



As to avoid this PLL jitter issue, Intel recommend to have a layout oversight with VCCST_VCCPLL routing over other power rails on Coffee Lake RVP #571506 and 573546.

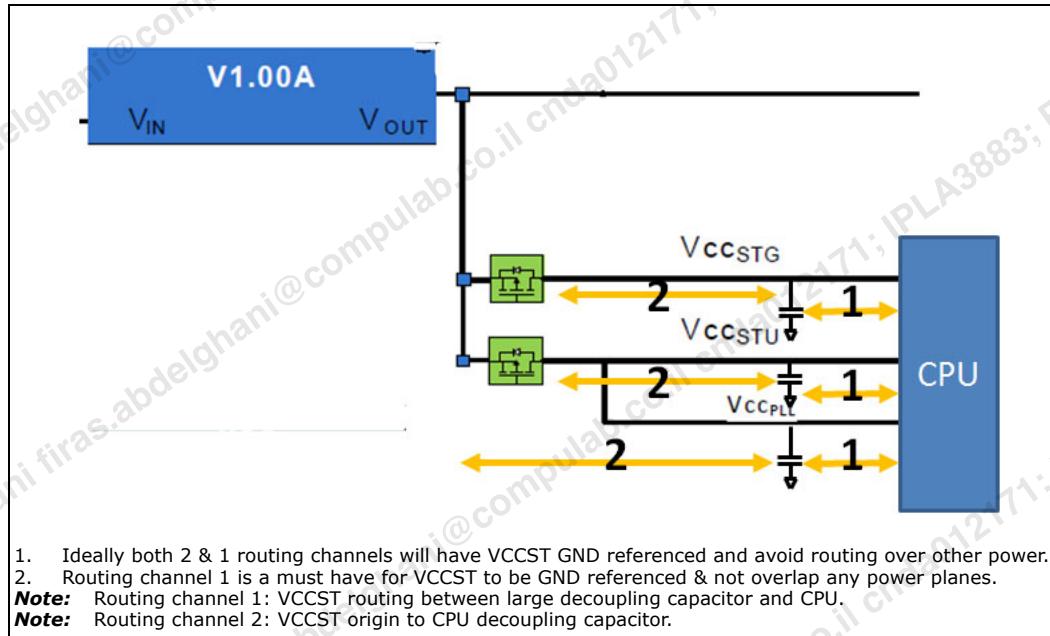
Note: Intel RVP does not follow the current PDG recommendations for VCCST, VCCPLL and VCCSTG

Customers should take care to only GND reference VCCST and VCCPLL from beginning to CPU.



50.1.3.1 CPU VCCST, VCCSTG, VCCPLL Power Routing Recommendation

CFL H CPU VCCST, VCCSTG, VCCPLL Power Routing Recommendation



50.1.4 Impedance Spectrum Tool (IST/IFDIM) Testing Requirements and Recommendations

Impedance Spectrum Tool testing requirements and recommendations are shown below.

Note:

IST/IFDIM is not directly available to customers, Intel will need these trigger points to support debug of customer issues at Intel validation labs. Intel recommends customers implement the IST tool requirements from this section.

Table 50-6. IST (IFDIM) Testing Requirements and Recommendations (Sheet 1 of 2)

Power Rail Sense Line	Feature	As Shown In	Required or Recommended	Notes
Vcc_SENSE / Vss_SENSE	Trigger signals	Table 50-7 and Figure 50-4	Required	Route to un-stuffed header as shown in Figure 50-4
	Current sense resistors	Figure 50-5	Recommended	One sense resistor per phase. VRTT loadline data is required if sense resistors are not provided
VccGT_SENSE / VssGT_SENSE	Trigger signals	Table 50-7 and Figure 50-4	Required	Route to un-stuffed header as shown in Figure 50-4
	Current sense resistors	Figure 50-5	Recommended	One sense resistor per phase. VRTT loadline data is required if sense resistors are not provided

Table 50-6. IST (IFDIM) Testing Requirements and Recommendations (Sheet 2 of 2)

Power Rail Sense Line	Feature	As Shown In	Required or Recommended	Notes
V _{CC_{SA}} _SENSE / V _{VSSA} _SENSE	Trigger signals	Table 50-7 and Figure 50-4	Required	Route to un-stuffed header as shown in Figure 50-4
	Current sense resistors	Figure 50-5	Recommended	One sense resistor per phase. VR TT loadline data is required if sense resistors are not provided

Note:

ITP/XDP uses the same MBP0 (xdp_bpm<0>) line. Recommend using steering resistors for trigger signal.

Table 50-7. Coffee Lake SKU IFDIM/IST Ballout Pins on Processor

	Coffee Lake SKU	Ballout Pin #'s and Names
1	CFL H BGA	BR27 or BPM#[0]
		E3 or IST_TRIGGER

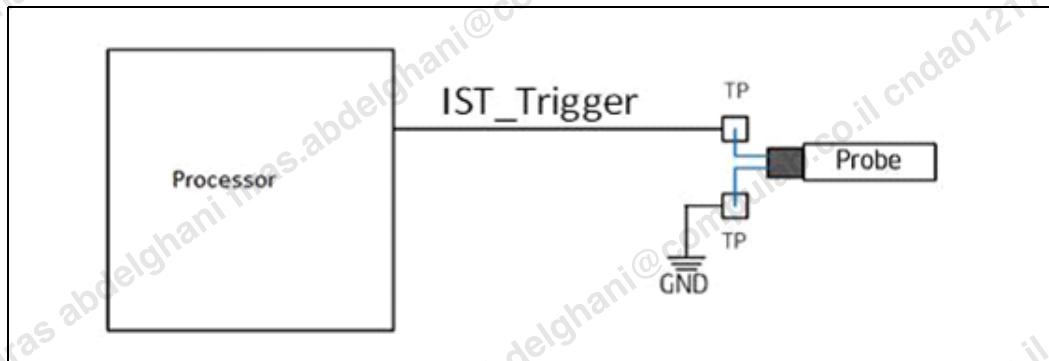
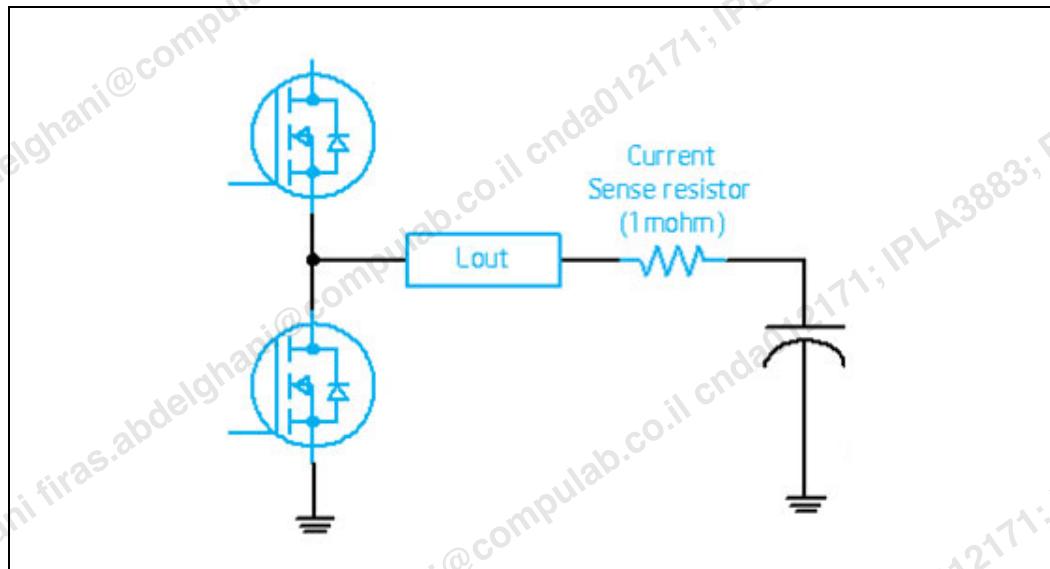
Figure 50-4. IST Trigger Point Implementation Requirement


Figure 50-5. Current Sense Resistor Recommendation

50.2 PCH Decoupling / Filter and Sense Point Recommendations

Follow decoupling capacitor requirements in the following table to ensure component maintains stable supply voltage. The capacitors should be placed as close to the package as possible in a location that would effectively decouple the pins listed under 'Place capacitors near balls'. Also, all decoupling capacitors need to have at least X5R rating. Pins listed under 'PCH Pins sharing power rail' are recommendations for pin group isolation and power plane routing. Intel recommends including pads for extra power plane decoupling capacitors for prototype board designs.

50.2.1 Power Plane Decoupling Recommendations

Refer to vendor's recommendation for exact VR output capacitor to meet the VR output target stated in Chapter 52, "Power Delivery"

**Table 50-8. Decoupling and Power Connection Requirements for CNL PCH-H (Sheet 1 of 2)**

Voltage Supply	Power Rails Pin Name	Pin Number	Edge Cap
V1.05A	VCCAPLL_1P05	B1, B2, B3, C1, C2	1x 1uF, 0402, 5mm
	VCCPRIM_1P05	E1, D1	1x 4.7uF, 0402, 5mm
	VCCA_BCLK_1P05	V19	
	VCCA_SRC_1P05	W19, W20	
	VCCA_XTAL_1P05	P2, P3	
	VCCPRIM_1P05	U26, U29, V25, V27, V28, V30, V31	1x 1uF 0402, 3mm 1x 22uF 0805, 5mm
	VCCAMPHYPLL_1P05	C49, D49, E49	1x 1uF 0402, 3mm
	VCCPRIM_MP PHY_1P05	W31	
	VCCDUSB_1P05	W22, W23	
	VCCDSW_1P05	BG45, BG46	
V1.8A/ PCH Integrated 1.8V VRM Note 3,5	VCCPRIM_1P8	AG19, AG20, AR15, AN15, BB11	1x 4.7uF 0603, 3mm when PCH Integrated 1.8V VRM is used or 1x 1uF 0402, 3mm when PCH Integrated 1.8V VRM is not used
	VCCPHVLDO_1P8	AF19, AF20	
N/A(PCH Integrated 1.8V VRM Output pin) Note 3	VCCPGPPD	AN24	
V1.8A/PCH Integrated 1.8V VRM Note3	VCCPGPPA	AN32	
V1.8A/V3.3A	VCCPGPPBC	AN26, AP26	
	VCCPGPPEF	AE35, AE36	1x 0.1uF 0402, 3mm (placeholder)
	VCCPGPPHK	AC35, AC36	1x 0.1uF 0402 3mm (placeholder)
	VCCPSPI	AN44	
	VCCHDA	BB14	
V3.3A	VCCPRIM_3P3	AW9, AY8, BB7, V23, AT44	1x 1uF 0603, 3mm Place close to AY8, BB7 pins.
	VCCPGPPG_3P3	AN21	
	VCCPDSW_3P3	BE48, BE49	1x 0.1uF 0402, 3mm (placeholder)
	VCCRRTC	BC49, BD49	1x 0.1uF 0402, 3mm 1x 1uF 0402, 5mm
V0.7-2.0V	DCPRTC	BG47, BF47	
N/A (Internal 1.24V LDO) Note 4	VCCDPHY_1P24	AJ22, AJ23, AK22, AK23	
		BG5	1x 4.7uF 0603, 5mm

**Table 50-8. Decoupling and Power Connection Requirements for CNL PCH-H (Sheet 2 of 2)**

Voltage Supply	Power Rails Pin Name	Pin Number	Edge Cap
V1.05	VCCMPHY_SENSE	K47	
0	VSSMPHY_SENSE	K46	

Notes:

1. All the edge caps need to be placed close to the power rails pin.
2. Refer Chapter 41 "Electromagnetic Compatibility" for recommended placement.
3. Refer to [Section 50.4.1.1](#) for CNL PCH-H Integrated 1.8V VRM usage guidelines.
4. Make sure AJ22, AJ23, AK22, AK23 are all shorted together on motherboard. Refer to [Figure 50-9](#) for implementation information.
5. Only 1 edge cap is required depending on the PCH Integrated 1.8V VRM implementation. Use 1x 4.7uF 0603 cap when PCH Integrated 1.8V VRM is used; Use 1x 1uF 0402 cap when PCH Integrated 1.8V VRM is not used.

Table 50-9. Filter Requirements for CNL PCH-H

Supply	Value	Quantity	Type	Notes
VCCA_XTAL_1P05 (Pin P2, P3) Note 1, 3	2.2 uH	1	Series Inductor 0603	Rated at least 100 mA DCR = 0.33Ω +/- 30%
	22 uF	2	Filter Capacitor 0805	X5R rating
VccAMPHYPLL_1P05 (Pin C49, D49, E49) Note 1, 3	2.2 uH	1	Series Inductor 0603	Rated at least 100 mA DCR = 0.33Ω +/- 30%
	22 uF	2	Filter Capacitor 0805	X5R rating

Note:

1. Placeholder only. Does not need to be stuffed.
2. All capacitors are edge capacitors unless labeled otherwise.
3. 2x 22uF 0603 caps can optionally be used instead of 1x 47uF 0603 caps. Caps should be with X5R temperature characteristics.
4. For LC Filter placeholder, the inductor should be replaced by a 0 ohm resistor.
5. Refer to [Figure 50-11](#) for routing information.

50.2.1.1 Alternate Capacitor Selection Considerations:

The MLCC decoupling recommendation listed in the PDG assumes 6.3V rated capacitors. It is recommended to use the capacitors with rated voltage at least 2 times the nominal voltage of the power rails.

When replacing the capacitors recommended in the PDG with different form factor/value capacitors, one needs to consider the capacitance derating, ESR and ESL difference from the original recommendation. Capacitor derating depends on many different factors, including temperature, DC bias, AC noise, voltage rating, etc. Smaller capacitors tend to have lower capacitance value after derating while in general the ESL is lower as well. Table [1] below shows an example of motherboard capacitor models (ESR/ESL and derated capacitance) used for 1V rails with 6.3V rated capacitors.

**Table 50-10. A capacitor Derating example**

Form Factor	Rated Capacitance	ESR (mW)	ESL (pH)	Derated Capacitance (uF)
0201	0.1uF	41.2	185.6	0.064
0201	1uF	13.1	158.0	0.601
0402	1uF	14.7	213.9	0.575
0402	10uF	8.4	237.9	6.057
0603	22uF	3.9	286.9	13.946
0603	47uF	3.2	279.4	28.901
0805	47uF	3.0	359.0	29.915

It is critical to understand the design constraints/limitation and ensure the alternative capacitor choice meets the same electrical requirement as the PDG recommendation.

Even though most of the rails can use 1 to 1 replacement ratio (i.e., using 1x 0201 to replace 1x 0402 capacitor with the same value), some sensitive rails may require 2 to 1 ratio.

50.2.2 VR Sense Requirements for PCH Rails

50.2.2.1 Sense Requirements for V1.05A

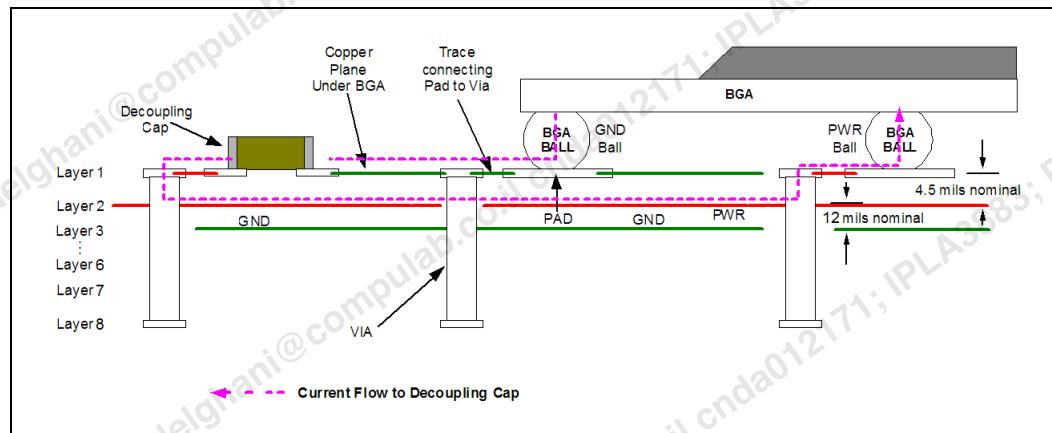
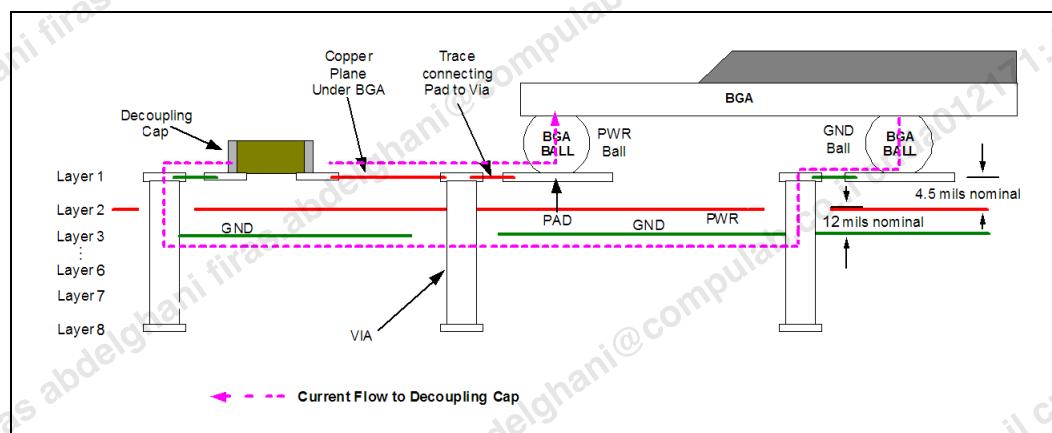
The sense point should be placed at the maximum 13 mm - 17 mm away from the MPHY pins. The width of this shape should be at least 15mils. This is required to meet the Vmin at the bumps.

50.3 Loop Inductance Reduction Decoupling

To reduce loop inductance and return path of for the decoupling capacitors, it is important to adhere to the (R)unway, and (E)dge decoupling capacitor placement recommended in [Figure 50-6](#) and [Figure 50-7](#).

The idea is to rotate capacitors that set over power planes so that the loop inductance is minimized. The basic theory for minimizing loop inductance is to consider which voltage is on layer two (power or ground) and spin the decoupling cap with the opposite voltage towards the BGA (Ball Grid Array). This greatly minimizes the total loop inductance.

The first figure below is an example of (R)unway decoupling capacitor placement, and the second figure is an example of (E)dge decoupling capacitor placement.

**Figure 50-6. Minimized Loop Inductance Example (R)unway****Figure 50-7. (E)dge Decoupling Capacitor Placement**

50.4

Power Plane Isolation

Customers must adhere to the following board design practices to address noise coupling concerns:

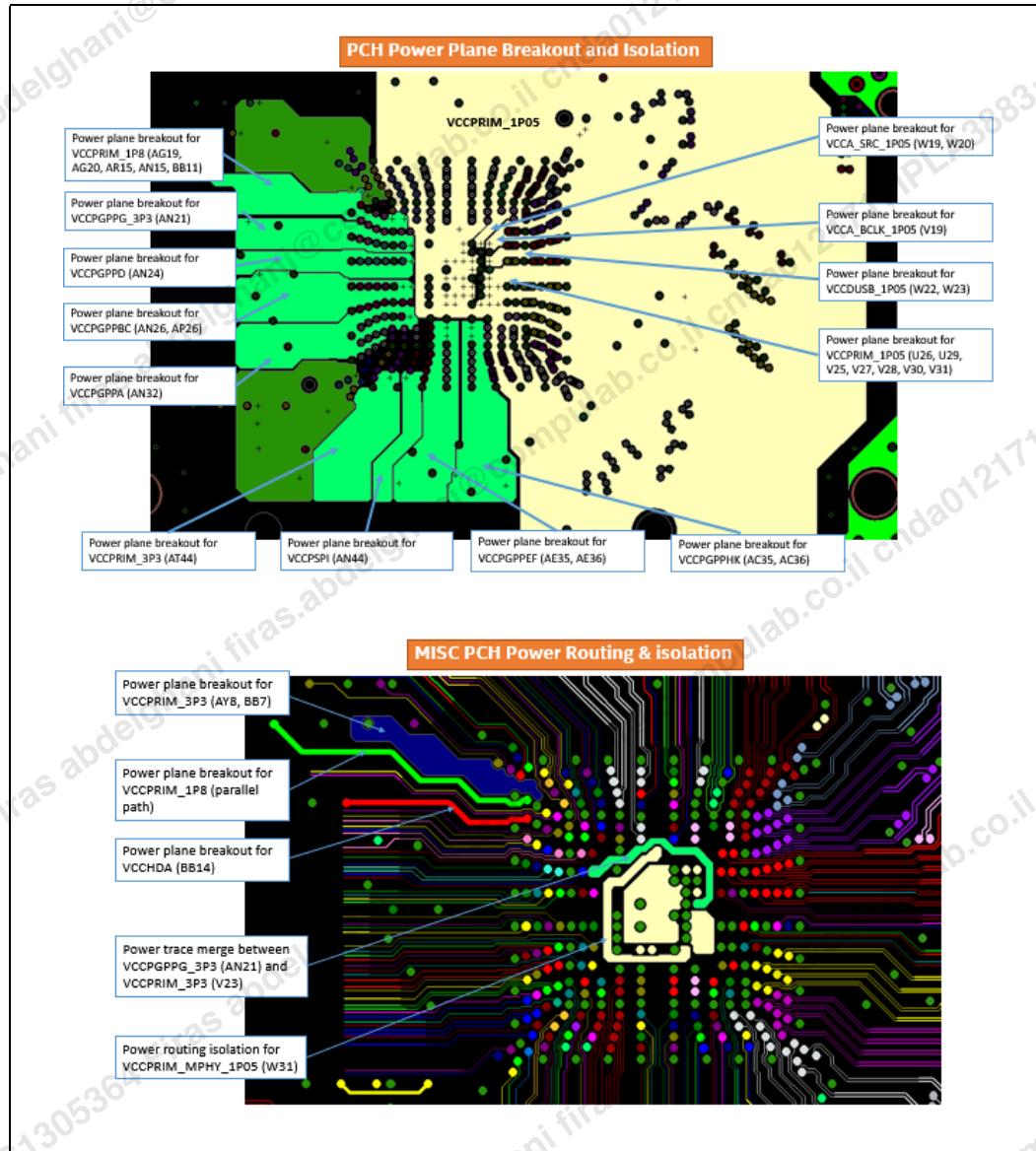
On the same layer, power plane isolation is required for different interfaces on the same power-rail (Example: Clock integration, mPHY, Core, PLLs). Minimum isolation-distance required is until the package edge.

- Avoid overlapping power planes on board stack-up, such as 3.3V referencing 1.05V plane. Reference GND as much as possible.

Power rail isolation is critical in power delivery design in order for proper noise isolation between interfaces. Proper grouping of ball pins and plane isolation for each interfaces is necessary even though they are sharing same voltage supply rail. Refer to [Section 50.4.1, "CNL PCH-H Power Rail Isolation and Routing Recommendations"](#) for more information.

50.4.1 CNL PCH-H Power Rail Isolation and Routing Recommendations

Figure 50-8. CNL PCH-H Power Rail Isolation Example



Note: Figure above shows the example of power plane isolation between VCC plane layer (L2) and some miscellaneous routing on layer 4 (L4) for a 4L board design.

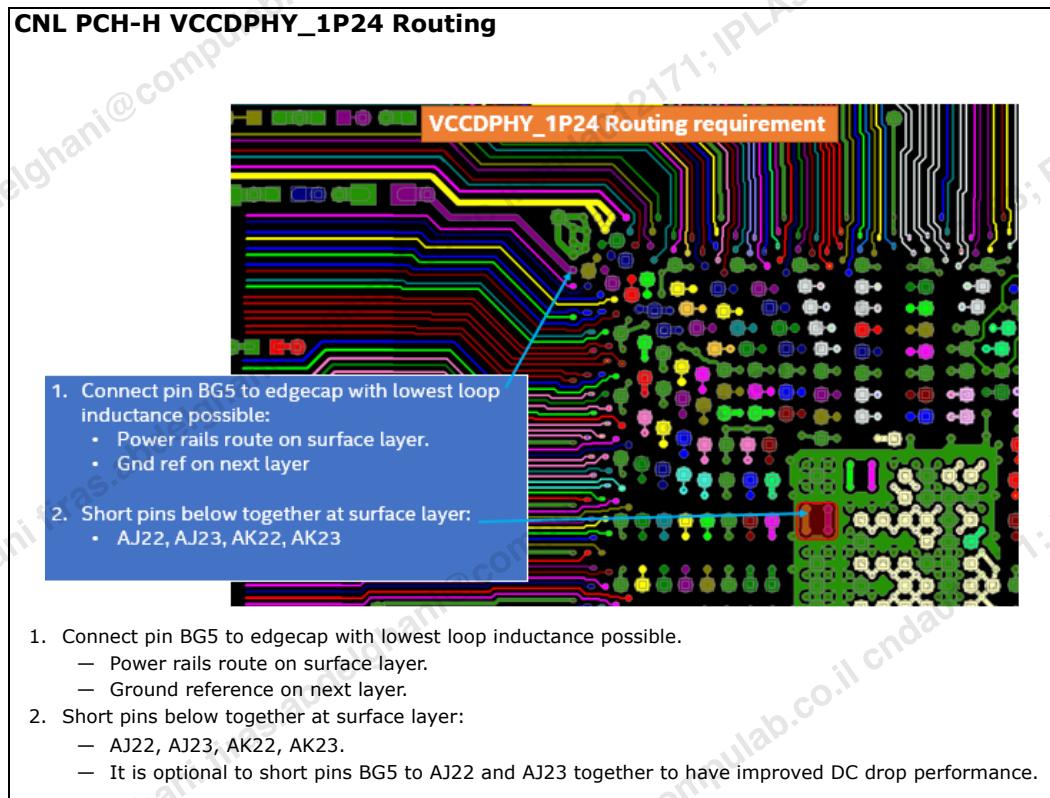
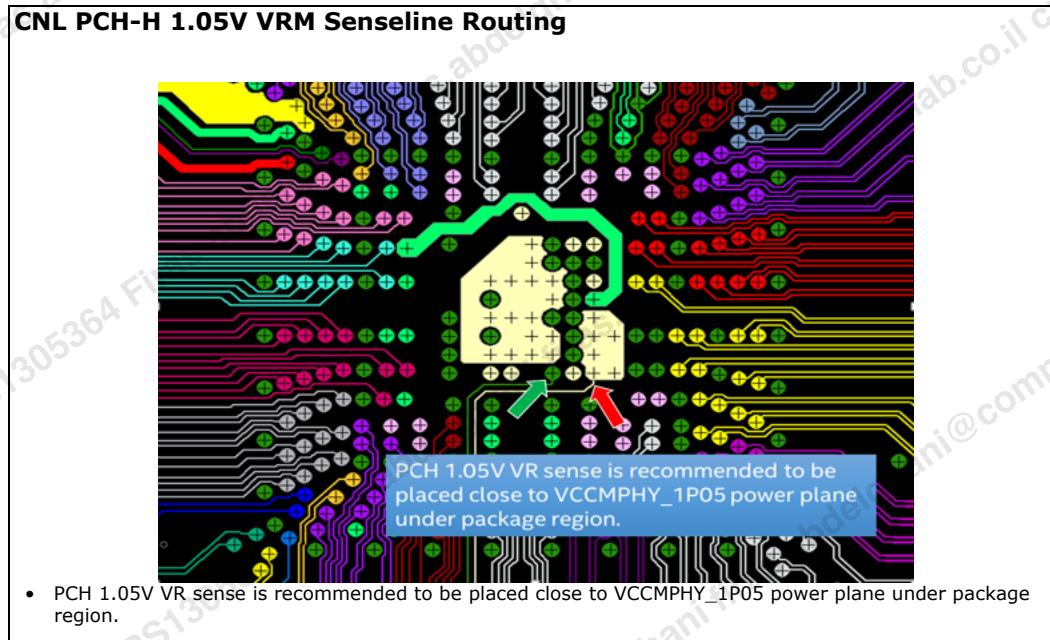
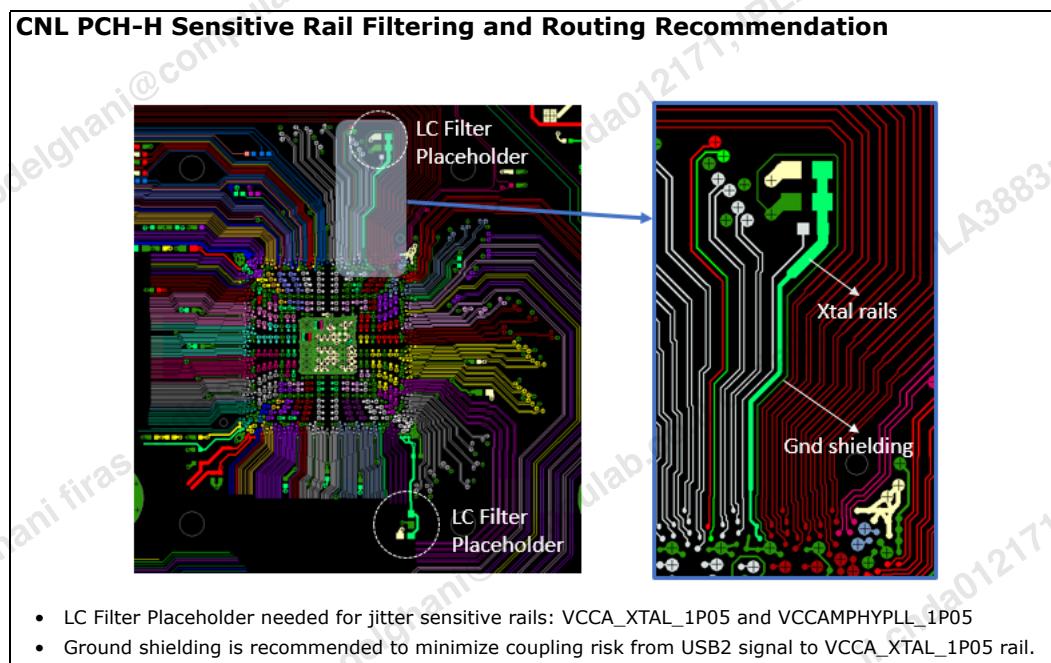
**Figure 50-9. CNL PCH-H Power Rail Isolation Example****Figure 50-10.CNL PCH-H 1.05V VRM Senseline Isolation Example**

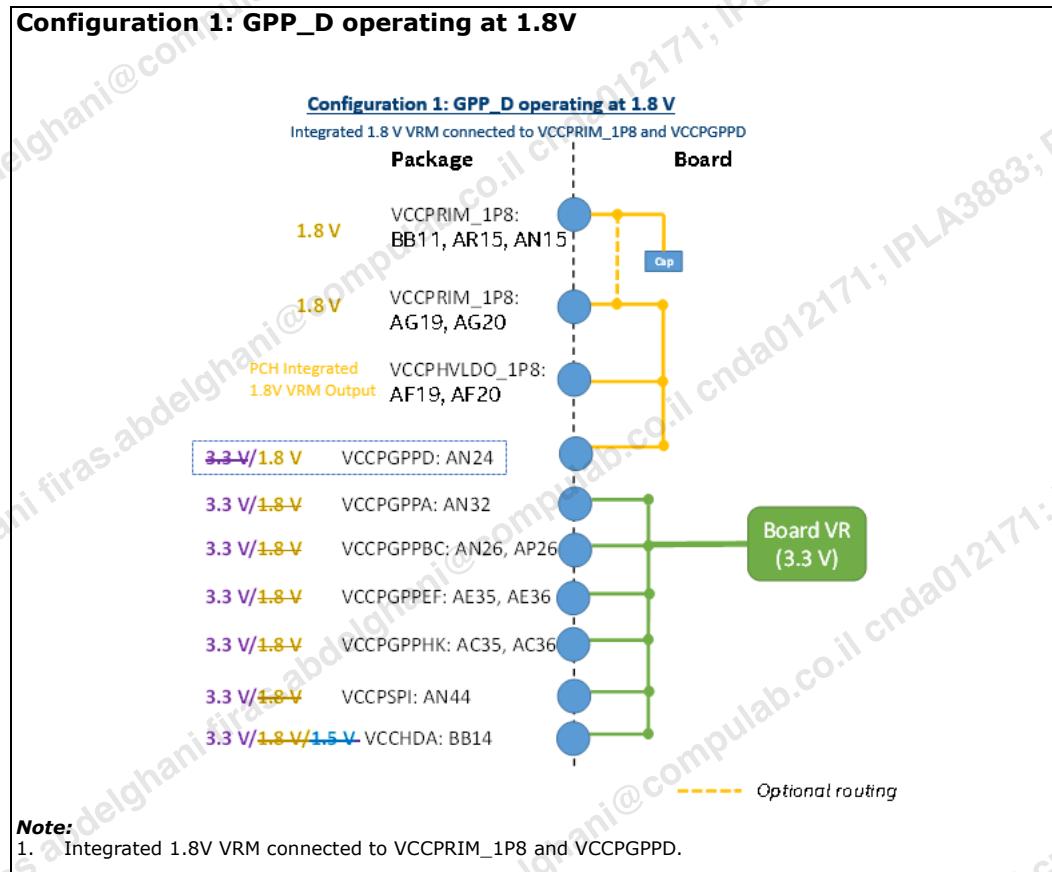
Figure 50-11.CNL PCH-H Sensitive Rail Filtering and Routing Recommendation

50.4.1.1 Cannon Lake PCH-H Integrated 1.8V VRM Usage Guidelines

The Cannon Lake PCH-H has an integrated 1.8V VRM using an integrated high voltage low dropout voltage regulator (HVLDO) which may be enabled to output 1.8V for use by the PCH as specified below.

- VCCPHVLD0_1P8 may be used to power VCCPRIM_1P8 if:
 - Platform does not implement 1.8V external VR connected to PCH.
- VCCPHVLD0_1P8 may be used to power both VCCPRIM_1P8 and VCCPGPPD if:
 - Platform does not implement a 1.8V external VR connected to PCH.
 - GPIO Primary Well Group D (GPP_D) is operating at 1.8V.
 - All GPP_D signals are operating in Native mode (instead of GPIO mode).
- Other usage requirements:
 - VCCPHVLD0_1P8 pin may not be connected to any other PCH or platform rail.
 - Platforms that implement a 1.8V external VR powering any of the 1.8V rails of PCH should leave the VCCPHVLD0_1P8 as No Connect. All PCH 1.8V rails should be powered by the external VR.

Figure 50-12.Scenario 1: Platforms without 1.8V External VR Connected to PCH Recommendation



**Figure 50-12.Scenario 1: Platforms without 1.8V External VR Connected to PCH
Recommendation**

Configuration 2: GPP_D operating at 3.3V

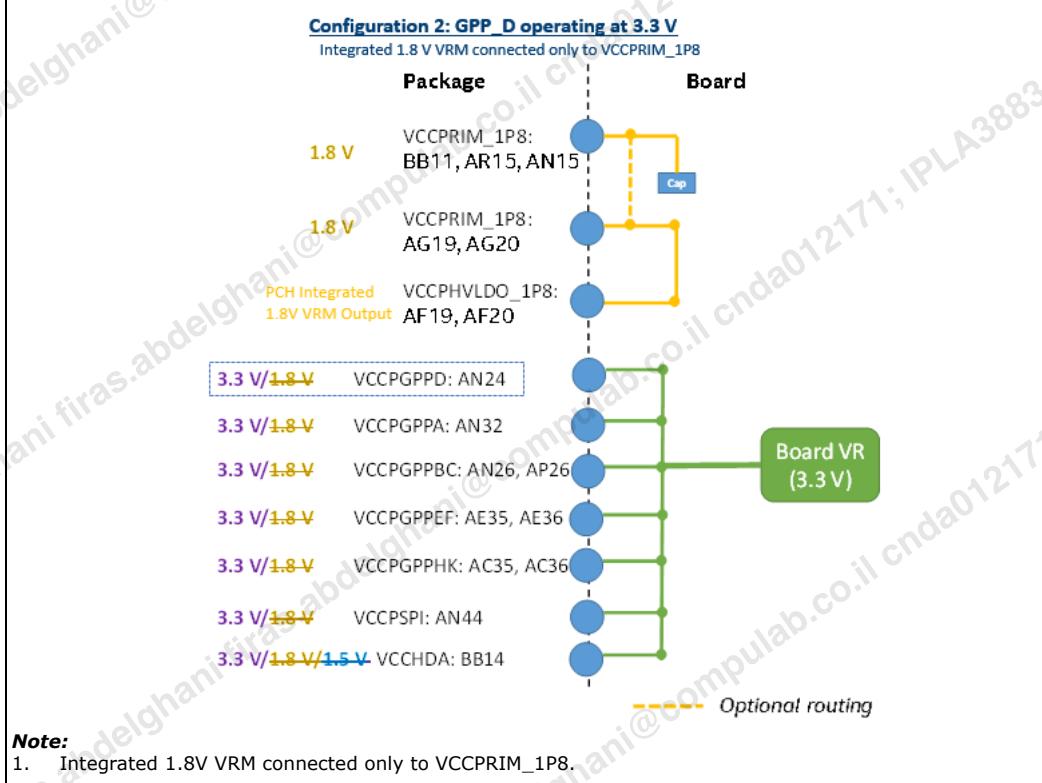
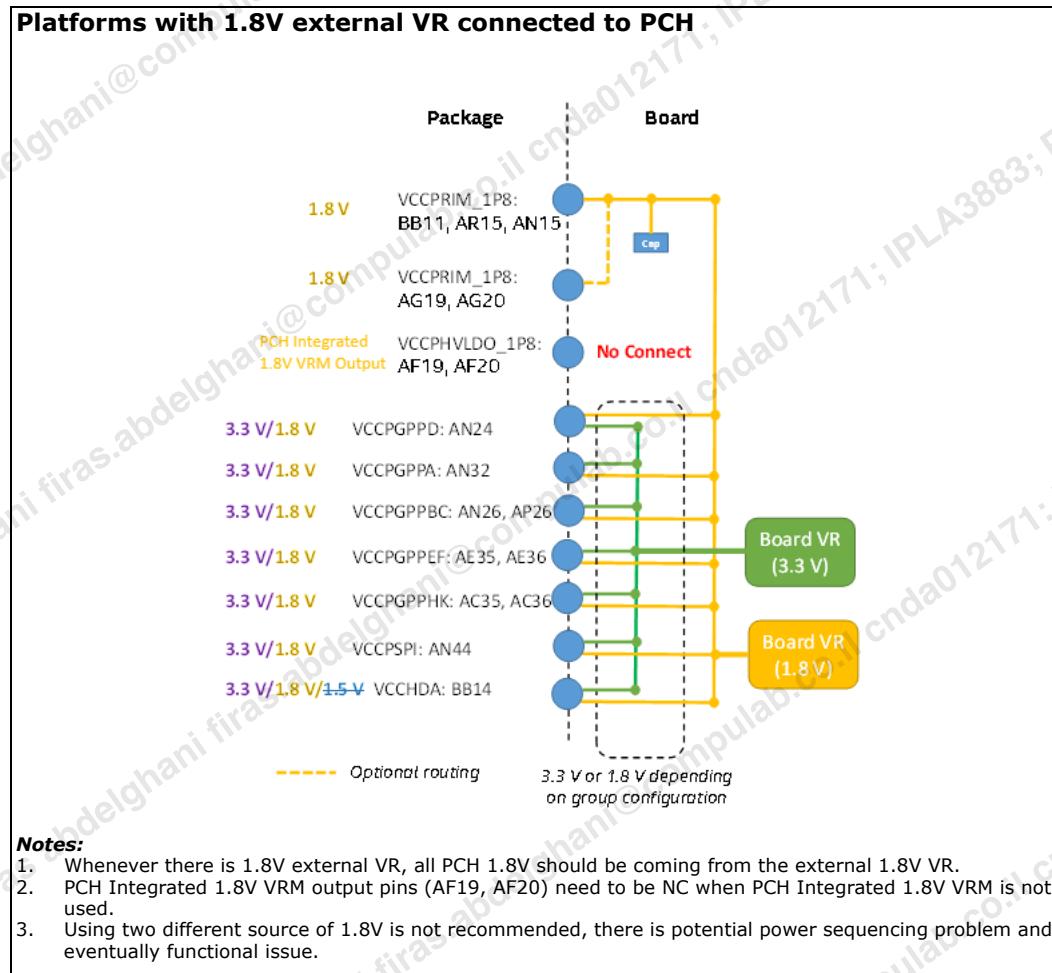




Figure 50-13.Scenario 2: Platforms with 1.8V External VR Connected to PCH Recommendation



50.5 Coffee Lake H Land Pattern Recommendations

Intel's land pattern guidance applies to PCB pad size and pad type design and is developed to maximize solder joint reliability mechanical performance and solder joint quality or SMT/manufacturing while still taking into consideration power delivery and power integrity requirements.

Table 50-11.Land Pattern Reference Document

Title	Document Number
Customer Knowledge Sharing: Land Pattern Design Best Known Methods	516635

Table 50-12. PCB Pad Definitions

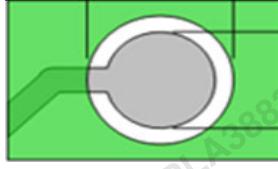
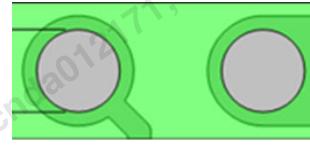
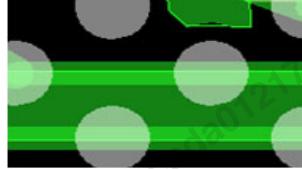
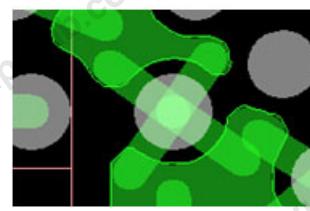
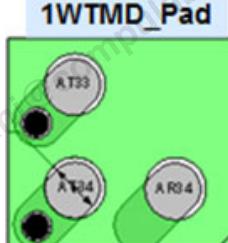
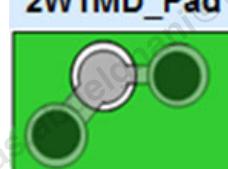
Pad Type	Definition	Description	Illustration
MD	Metal Defined	Traditional dog bone via to BGA-pad. IO driven, trace width usually determined by impedance.	
SMD	Solder Mask Defined	Pad 100% defined by solder mask, flood and/or metal trace > pad diameter.	
½ MD	Half Metal Defined	50% pad is metal defined and the other 50% pad is solder mask defined.	
Spoke (X or +)	Spoke pad	Multiple traces connecting pad to nearby flood plane. Used for improved reliability or manufacturability where flood plane is needed.	
WTMD	Wide Trace Metal Defined	Trace = pad diameter or less. 1WTMD = 1 wide trace to BGA pad.	
		2WTMD = 2 wide trace to BGA pad. Total thickness of traces should not cover more than 50% of pad circumference (T1 width + T2 width < 50% circumference).	



Figure 50-14.Coffee Lake H-Processor Land Pattern Guidance

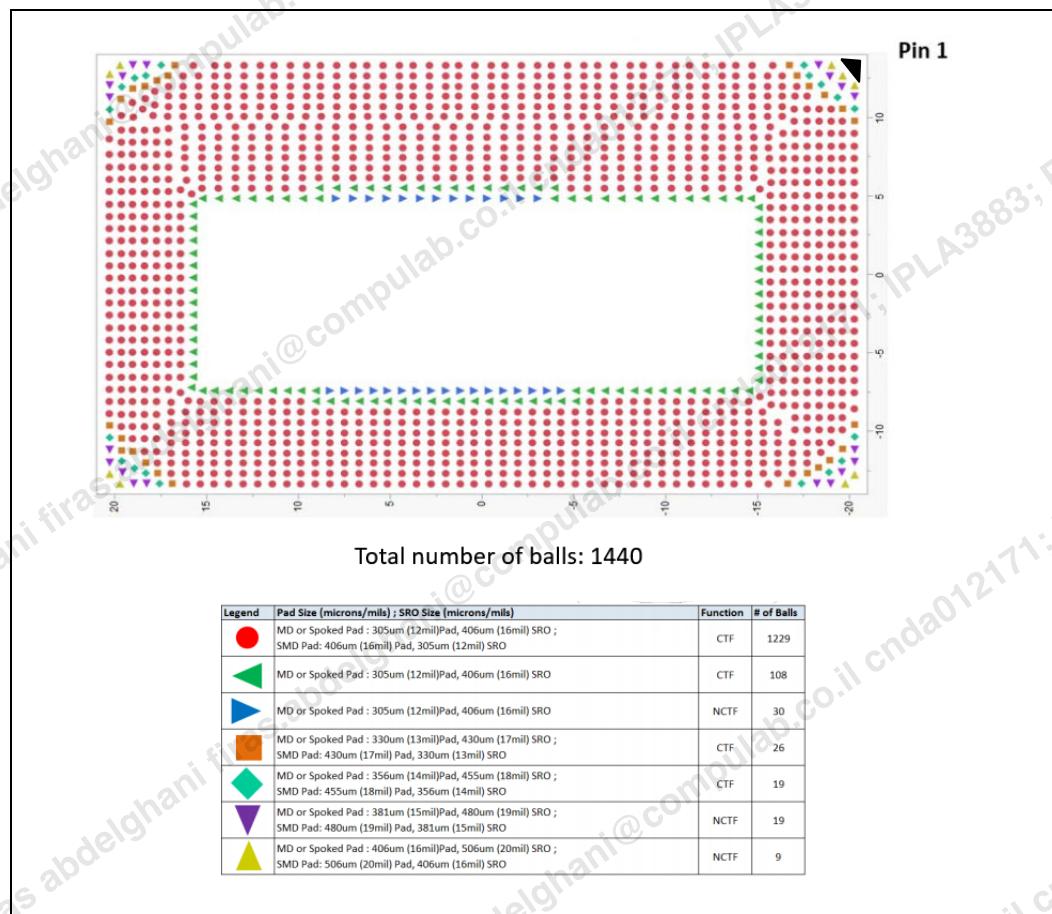
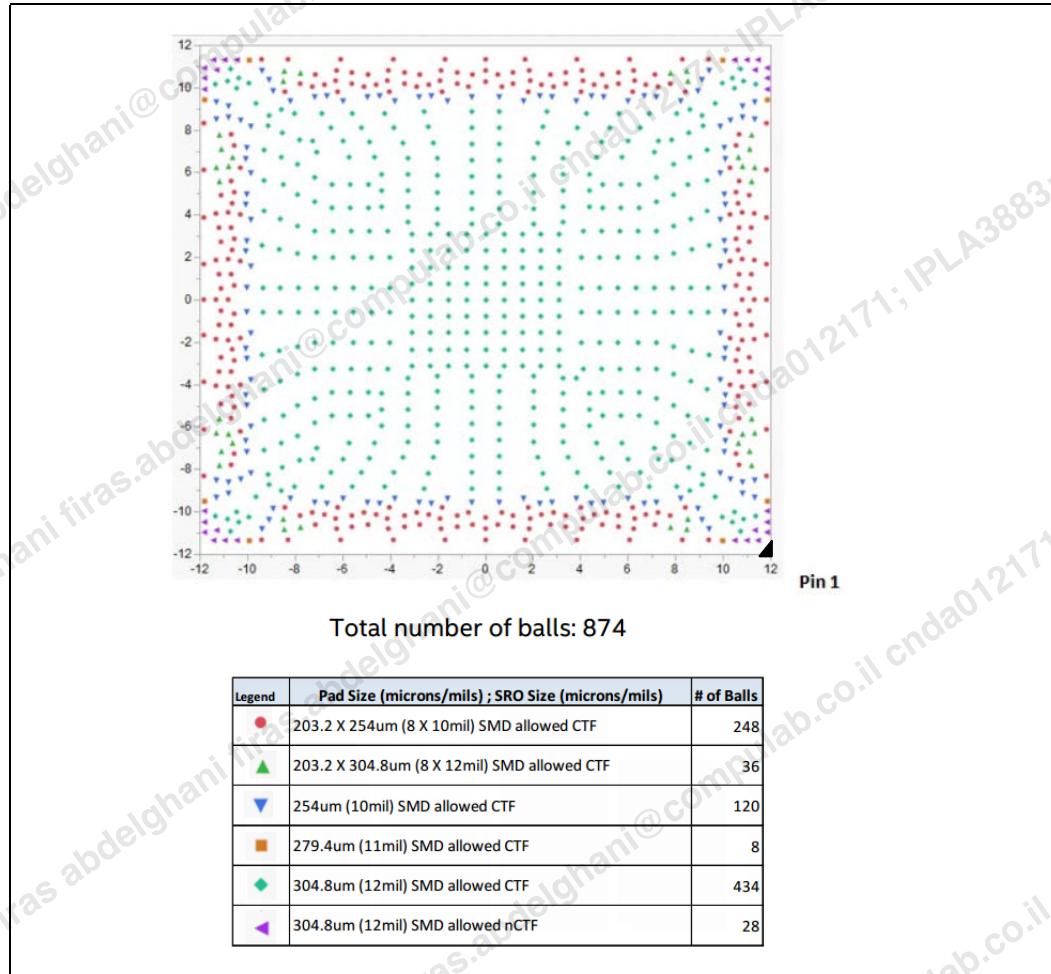


Figure 50-15.Cannon Lake PCH-H Land Pattern Guidance

§ §



51 Power Delivery

This chapter provides guidelines for the Coffee Lake platform power delivery solution. The platform power delivery is comprised of an IMVP8 voltage regulator (VR), Rest of Platform (ROP) VRs, load switches, battery charger, battery and fuel gauge, AC/DC adapter, power and current monitors, USB Type C power delivery and Power Sequencing.

- IMVP8 VR(s) regulate power to the CPU and graphics core of the processor. Details are provided in [Section 51.2](#).
- Rest of Platform (ROP) VRs regulate power to the PCH and rest of the system components. Discrete VRs or a PMIC can be used to supply ROP rails. Details are provided in the Power Map [Section 51.1](#).
- Load Switches gate power to various SoC and ROP blocks to save power. Details are also provided in the Power Map [Section 51.1.2](#).
- Battery Charger considerations are discussed in [Section 51.6](#).
- Battery Fuel Gauge considerations are discussed in [Section 51.8](#).
- AC/DC Adapter considerations are discussed in [Section 51.5](#).
- P_{SYS} , the System Input Power Monitor is discussed in [Section 51.7](#).
- USB Type C Power Delivery is covered in [Chapter 20](#)
- Power Sequencing is covered in [Chapter 45](#)

51.1 Power Maps

51.1.1 Power Map Tool

The Platform Power Map diagrams key specifications of the voltage regulators (IMVP8 and ROP VRs), load switches and the loads. To provide more flexibility in power design, power maps are now provided as a separate configurable tool. This tool is also where Default and Extreme power limits (PL2, PL4) are provided. Refer to Coffee Lake H Platform Power Map Design tool to generate a power map that accompanies this section. The Power Map tool will be in the same collateral list as this document on www.intel.com.

Note: **The processor and PCH EDS specification documents take precedence and will override any conflicts with what is being stated herein.**

51.1.2 Load Switch Sizing

For SoC power rails requiring load switches, platform designers will need to select a load switch with an appropriate resistance/ R_{dson} target to ensure that the voltage specifications at the SoC are met. As a general rule of thumb, the IR drop across the load switch should not exceed more than 1% of the voltage supply value under I_{ccmax} conditions. Platform designers can adjust this target higher or lower to optimize the



load switch selection for a specific motherboard design based on parameters such as the tolerance of the sourcing VR design, the resistance of the layout path from the VR to the load switch and finally to the CPU, VR sense location, etc.

51.1.3 Trade-offs - Volume vs. Premium Power Maps

Power maps are broken into two tiers: Volume and Premium. Volume focuses on cost savings with the fewest VRs and Premium focuses on the smallest solution size with the lowest power consumption. For a design focused on S0ix or Modern Standby* power, the Premium power map is recommended. The designer may choose to implement a hybrid between Volume and Premium as long as guidelines are followed.

Table 51-1. Differences between Power Maps

Volume	Premium
VccST gated by SLP_S4#	VccST gated by SLP_S3#
Various system devices share load switches	Various system devices have their own independent load switches
VccPLL_OC is supplied directly from VDDQ	VccPLL_OC is supplied from VDDQ through a load switch

Note: Other changes may be present. Refer to the Power Map tool for details.

Estimated power deltas of each SoC load between different configurations is shown in table below.

Table 51-2. Estimated Power Deltas between Different Configurations

Configuration		Estimated SoC Power Delta from Config #1 to #2
Config #1 (Premium)	Config #2 (Volume)	CFL H
VccST off in S3	On in S3	+25-30mW
VccPLL_OC off in S0/C10	On in S0/C10	+3-10mW
VccPLL_OC off in S0ix	On in S0ix	+3-10mW

Other than what is documented in the table above, there is no expected SoC power delta in Sx states between Volume and Premium configurations. Independently, implementing Deep Sx (also known as DSW) may lower platform power over traditional Sx.

CPU_C10_GATE# is a signal from the Coffee Lake SoC that can be used for gating off VccSTG, VccPLL_OC and VccIO (CFL H) in the S0/C10 system state in order to save power.

Ensure fast ramp-up timing requirements can be met as described in [Section 45.4.1, "Power Sequencing Timing Requirements"](#)

To save power in S0 idle (for example Windows* idle), it is recommended to power gate VccSTG in the S0/C10 state even in "Volume" designs. VccSTG should be gated by {SLP_S3# AND CPU_C10_GATE#}.



VccPLL_OC must be powered off whenever VccST is off.

Table 51-3. Enable Signal Implementations for VccST and VccPLL_OC

VccST Load Switch Enable	Supported VccPLL_OC Load Switch Enables
SLP_S3#	SLP_S3#, or {SLP_S3# AND CPU_C10_GATE#}
SLP_S4#	No gating required (tied to VDDQ), or SLP_S3# , or {SLP_S3# AND CPU_C10_GATE#}

Both Premium and Volume configurations can be used for systems that support the S0ix / Modern Standby state however power may be higher in that state with the Volume configuration.

Platform/silicon debug functionality may require that some platform rails be powered up in states where they would normally be unpowered under a normal usage scenario. Platforms that require the ability to use this debug functionality must support powering the proper rails in the proper power states.

51.1.4 VccSTG Rail Discharge Requirements

As long as VccST and VccSTG are power gated separately, the following requirements are critical to prevent system failure on Coffee Lake:

1. VccSTG should have a discharge circuit, either integrated into its load switch or externally on the motherboard. The recommended nominal $R_{\text{discharge}} \leq 300\Omega$ to GND. The discharge circuit should be activated when the VccSTG load switch is disabled.
2. If VccST/VccPLL has a discharge circuit, either integrated into its load switch or externally on the motherboard, then VccSTG nominal $R_{\text{discharge}} \leq V_{\text{ccST}}/V_{\text{ccPLL}}$ $R_{\text{discharge}}$.
3. The total capacitance on VccSTG \leq total capacitance on VccST/VccPLL.

51.2 Processor Power Delivery Guidelines

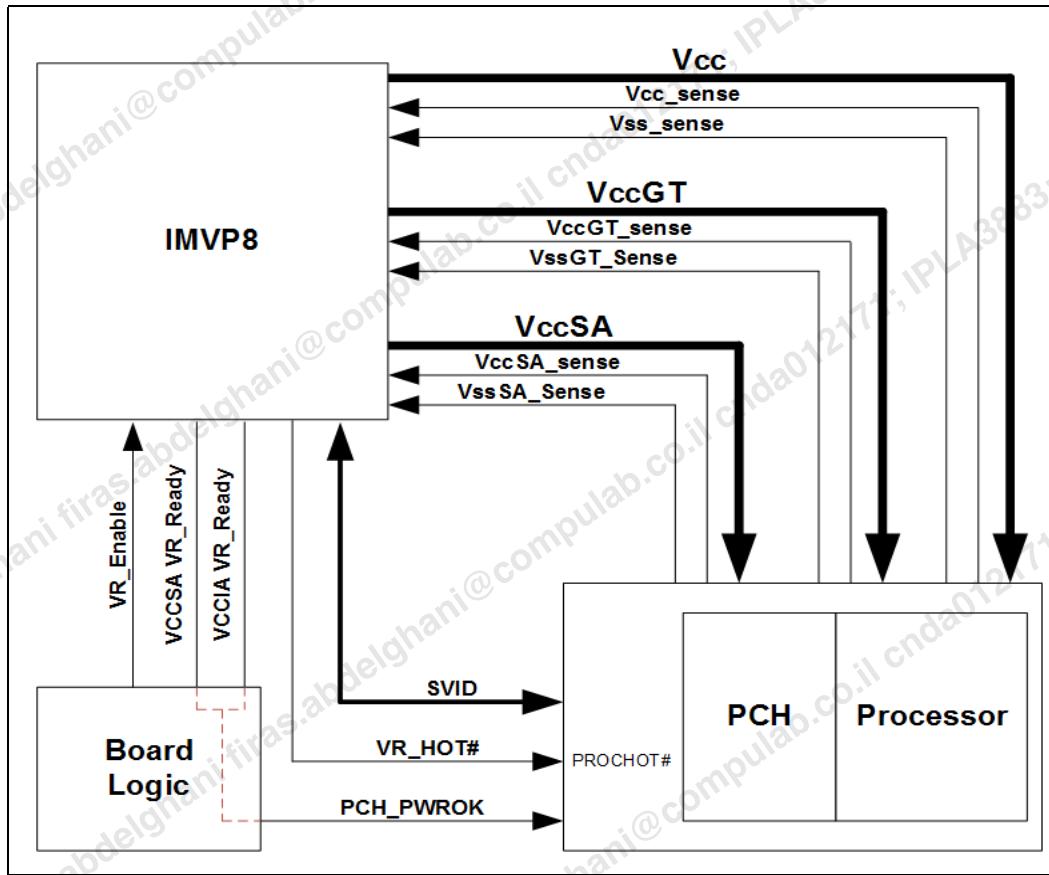
This section provides the general processor voltage rail design guidelines.

51.2.1 General Processor Power Delivery Considerations

An IMVP8 VR regulates power to the processor core. The IMVP8 Pulse Width Modulation (PWM) Specifications define the DC-DC VR electrical requirements.

CFL H uses IMVP8 to power the processor, graphics, and system agent.

Figure 51-1 is a generic representation of the IMVP8 VR. Other features and implementations are definitely possible.

Figure 51-1. IMVP8 VR Block Diagram


Important points to note in these block diagrams are:

- IMVP8 requires differential remote sensing. Differential sense inputs for a given rail must be the ONLY feedback point back to controller. Refer to [Table 51-4](#).
- VR_Ready is a required controller output signal. It indicates that VR is operational. VR_Ready signal is also used for appropriate power up sequencing during a platform boot.
- IMVP8 compliant controller is required to provide VR_HOT# (VR Thermal Throttling) output signal to indicate operation close to regulator maximum thermal limit. It is used by the system to prevent catastrophic thermal damage.
- VR_ENABLE (IMVP8) is required signal provided by platform logic. It enables the outputs of IMVP8 regulators.

51.2.2 Testing and Validation

The nominal processor voltage is determined by an SVID code provided to the VR. The VID nominal value indicates the reference point that the VID provides for the static and ripple voltage tolerance. Due to VR tolerances, PCB parasitic and current draw variations, the average voltage seen at the processor may be slightly higher or lower than the reference value according to the loadline spec or tolerances.



The VR must meet the static, ripple, and loadline tolerance limits for the entire range of processor load. Loadline, static and ripple tolerance window specifications must be met as measured differentially at Vcc_SENSE/Vss_SENSE pins.

Frequency Domain Impedance Measurement (FDIM) testing is also expected to be completed up to 1MHz on every IMVP8 power rail.

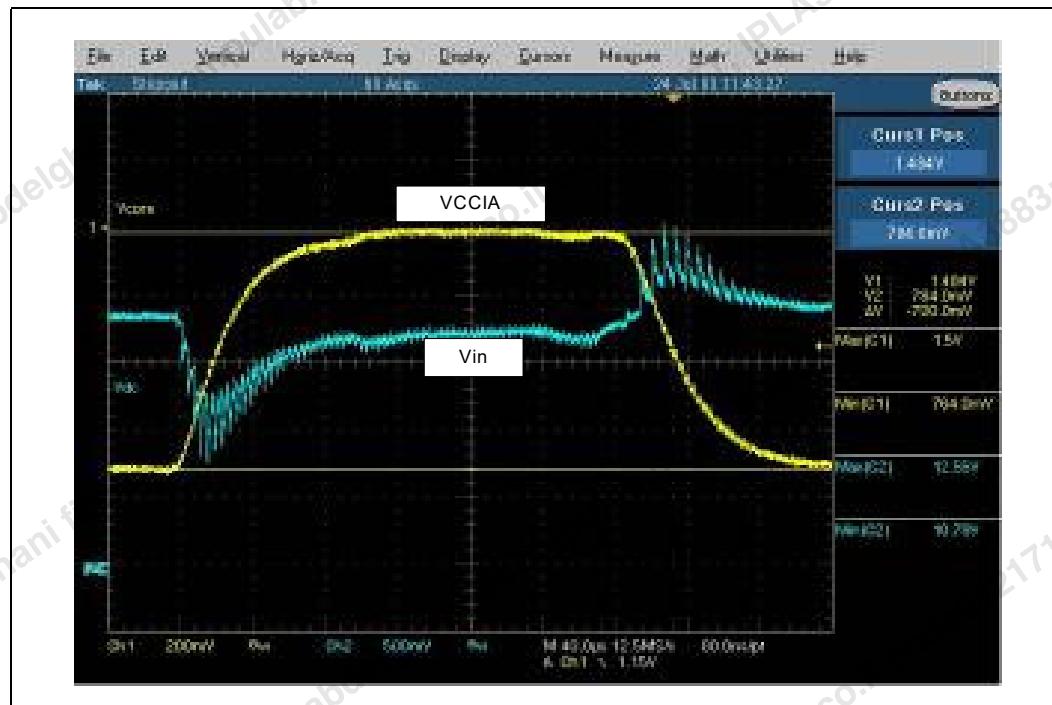
Refer to *Coffee Lake Platform Power Validation Plan* for guidance on validating power delivery and FDIM test requirements.

51.2.3 Audible Noise Reduction

At least three conditions need to be simultaneously present for acoustic noise. They are periodic dv/dt in the audible range, sufficient dv magnitude, and insufficient damping, e.g. typical of a heavily-reliant or all-MLCC decoupling solution. The noise amplitude increases with current in $I = C * dv / dt$.

Ways to minimize the acoustic noise are:

- Control the in-rush current by sizing the output capacitor to just meet the transient requirement without excess
- Proper selection of inductors; taking core material, construction, mechanicals, and mounting into account to mitigate any potential inductor-induced "buzz" noise.
- Low-ESR MLCC's are notorious for potential audible noise, especially when exposed to large dv/dt events. This is due to the Piezo effect. The noise magnitude is proportional to the number of MLCC's used. Potential steps to take are:
 - Buck Regulator Input Filter. The highest peak-to-peak voltage/current stresses (dV/dt, dI/dt) of a Buck regulator are handled by the input filter caps
 - The input filter MLCC's should be (2) 4.7µF X5R per phase
 - Avoid Y5V dielectric MLCC's, as experience shows them more susceptible to the Piezo effect
 - Physical placement is important, e.g. co-locate MLCC pairs either side of the input FET, not side-by-side
 - Increase the capacitance to 10uF if needed to minimize the noise
 - Where possible, large input bulk capacitors should be used-(2) 680 µF or larger-to minimize the dv/dt events
 - Buck Regulator Output Decoupling
 - For output high frequency decoupling, use 22µF or higher valued MLCC's to reduce the number of needed capacitors
 - Use polymer chip capacitors in conjunction with MLCC's, when possible
 - Placing MLCC's symmetrically on the top- and bottom-sides of the motherboard introduces mechanically-opposed forces, helping mitigate any vibration, and reducing the noise magnitude

Figure 51-2. Input Voltage Droop Caused by dv/dt Event at Output


51.2.4 Vcc_SENSE/Vss_SENSE Package Sensing

Motherboards are subject to layout area constraints that could significantly compromise a VR's placement on the motherboard and its connection to the processor pins. To ensure that the power delivery network's (PDN) impedance profile stays at/below the maximum loadline target for frequencies above the VR's Gain-Bandwidth (G-BW), the placement and connection of the decoupling capacitors as well the shapes of the power plane(s) is critical. At frequencies within the VR's G-BW control, the VR layout placement may be compensated using remote sensing of the voltage at the die through Vcc_SENSE/Vss_SENSE signals.

The processor implements the concept of "package sensing" for IMVP8 voltage rails; the following examples use Vcc/Vss as general labels. Note: for optimal performance and noise rejection, the feedback signals for the IMVP8 controller should be routed as if they are a differential pair connecting the Vcc and Vss bumps of the processor to the IMVP8 controller Vcc_SENSE and Vss_SENSE pins respectively. This is true for non-IMVP8 rails too. This implementation extends the VR controller's regulation range, enclosing the motherboard parasitics within its feedback loop minimizing the impact on voltage regulation. The conceptual implementation of Vcc_SENSE/Vss_SENSE package sensing is illustrated in Figure 51-3 with recommendations in Table 51-4.

Table 51-4. Package Sensing Recommendations

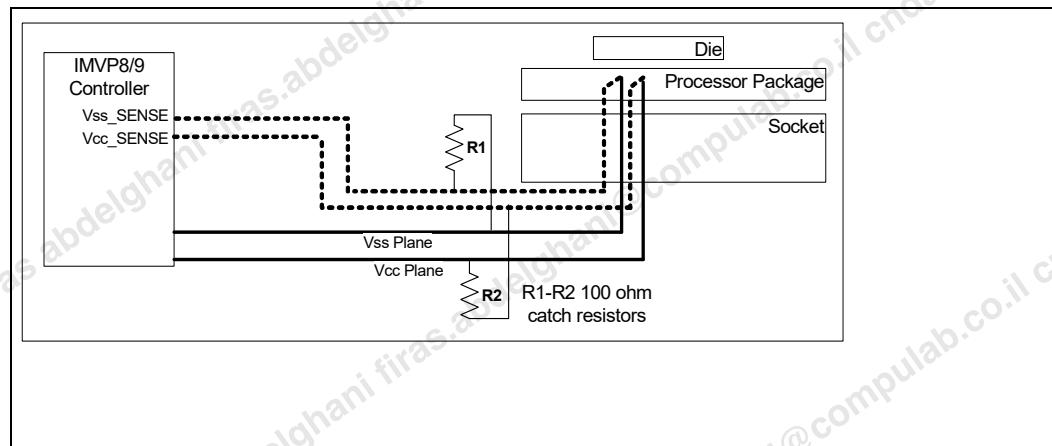
Power Rail Sense Line	R1,R2	Trace Impedance	Trace Length Match
Vcc_SENSE / Vss_SENSE	100Ω	50Ω	<25 mils
VccGT_SENSE / VssGT_SENSE			
VccSA_SENSE / VssSA_SENSE			
VccIO_SENSE / VssIO_SENSE ^[1]		NA	

Note:

- Does not apply when rails are merged.

To minimize any stray noise pickup to the Vcc_SENSE/ Vss_SENSE lines

- Sense traces should be referenced to a solid ground plane
- Avoid crossing over plane splits
- Maintain 25-mil separation distance away from any other dynamic signals

Figure 51-3. Example of Processor Vcc_SENSE/Vss_SENSE Package Sensing

- Figure above demonstrates the purpose/function of the feedback "catch" resistors. As discussed above package sensing effectively encloses the board parasitics within the feedback loop of the VR; however, a problem arises when the DUT is not present; the feedback loop is open and the VR does not have any feedback. Aberrant or unstable VR behavior may result, including overvoltage, errant/sporadic VR operation, etc. This may potentially damage motherboard components like the bulk decoupling capacitors. The "catch" resistors serve to close this feedback path, "bypassing" the Vcc_SENSE/Vss_SENSE connections through the processor and providing the necessary closed-loop feedback to the VR.
- Operation: The processor Vcc_SENSE/Vss_SENSE package traces are shunted to the motherboard Vccx and Vssx planes via the catch resistors R1 and R2. R1 and R2 are sized large in relation to the sense lines impedance so not to cause error when the DUT is present.
- Some additional guidelines:



- R1, R2 should be placed within 2 inches (50.8 mm) of the processor socket, minimizing any potential error due to Vcc_SENSE/Vss_SENSE line resistance.
- Preserve the transmission line integrity of Vcc_SENSE/Vss_SENSE lines by avoiding stub routing to R1, R2 catch resistors.
- Note: For systems using a BGA packaged processor catch resistors are optional.

51.3 IMVP8 Voltage and Current Requirements- H-Line

An IMVP8 compliant VR supplies the required voltage and current to the processor's IMVP8 based voltage rails of a single processor. The VID nominal value indicates the reference point for the static and ripple voltage tolerance.

Each IMVP8 VR output must meet the specifications in the processor EDS at remote sense processor pins.

Due to VR tolerances, PCB parasitic and current draw variations, the average voltage at the processor may be slightly higher or lower than the reference value. However, the VR must meet processor static and ripple tolerance limits over the entire range of processor load. The following conditions apply to the specifications:

- Applies to all frequencies unless specific frequencies are listed
- Applies to full temperature range
- I_{CC} is measured at the nominal VID Vcc value under maximum signal loading conditions such as running a power virus program.
- Applies to full input power rail range
- The nominal VID voltage, voltage tolerance, and maximum current values are for reference only. Refer to the appropriate component documentation for the most current specifications.

An IMVP8 compliant VR must be designed to:

- Temporarily support "IPL2" currents during a PL2 event for the respective tau duration their VR can thermally support.
- Momentarily support the processor's maximum current (VR's electrical design constraint)
- Operate within spec under the worst-case dynamic/loaf transient events

Refer to the processor's EDS for detailed processor specifications. Values shown in this document represent voltage plane design guidelines, not processor specifications.

Table 51-5. General Processor VR Parameters for CFL H62, CFL H42 and CFL H82 (Sheet 1 of 2)

Symbol	Description	Parameter Values	Notes
VCC,VCCGT, VCCSA,VID	VID Range	0 V-1.52 V	
VCC, VCCGT VBoot	VBoot Setting	0V	



Table 51-5. General Processor VR Parameters for CFL H62, CFL H42 and CFL H82 (Sheet 2 of 2)

Symbol	Description	Parameter Values		Notes	
VCCSA VBoot	VBoot Setting	1.05V			
VID1	Test VID	0.9V			
VID2	Test VID in Low Freq Mode	0.6V			
VID3	Test VID in PS3	0.3V			
Icc_PS1	Max Current in PS1 state	20 A			
Icc_PS2	Max Current in PS2 state	5 A (4A max transient)		Transient loads will be from 1A to 5A	
Icc_PS3	Max Current in PS3 state	1 A		Transient loads are not expected	
+/- ripple (mV)	PS0, PS1, PS2, PS3	0 A < Load ≤ 0.5 A	+30mV/ -10mV		
	PS0	0.5A < Load ≤ I _{TDC}	+/- 10mV		
		I _{TDC} < Load ≤ I _{ccMax}	+/- 15mV		
	PS1	Load > 0.5 A	+/- 15mV		
	PS2	Load > 0.5 A	+30mV/ -10mV		
	PS3	Load > 0.5 A	+30mV/ -10mV		
V_TOB_Imin (mV)	VID1	+/- 5		See Note 3 and 4	
	VID2	+/- 8			
	VID3	+/- 8			
V_TOB_Imax (mV)	PS0	+/- 20			
	PS1	+/- 20			
	PS2/ PS3	+/- 20			
Max Slew rate	For VID changes <= 50mV	200 mV/us			
	For VID changes > 50mV	90 mV/us			
R_DC_LL (mV/A) MAX	Loadline slope within the VR regulation loop capability 0-1kHz	VCC	1.8	Load line slope within the VR regulation loop capability 0-1kHz	
		VCCGT	2.7		
		VCCSA	10.3		
R_AC_LL (mV/A) MAX	Loadline slope in response to dynamic load increase events 1kHz-1MHz	VCC	1.8	Load line slope in response to dynamic load increase events 1kHz-1MHz	
		VCCGT	2.7		
		VCCSA	10.3		

Notes:

1. Refer to applicable processor Electrical Design Specification (EDS) for latest electrical parameters.
2. Processors will spend more time operating at thermal design point. VR should be designed to efficiently deliver power at TDC and beyond.
3. These are Intel default values and are used in the calculation of Min and Max LL slope tolerances in this table. Values obtained from the VR vendor based on the VR design may be used here as well, but they will change the calculation results.



4. Icc_PS1, Icc_PS2 and Icc_PS3 values are default settings. Consult BIOS Writers Guide ([Chapter 1, "Introduction"](#)) for possible methods to overwrite them. Icc PS1 max current should not exceed the domain

Table 51-6. Processor VR Overshoot values

Parameter	Vcc		Vcc _{GT}	Vcc _{SA}
	IccMAX_App transients	IccMAX transients	IccMAX transients	IccMAX transients
VOvS_Max (Max overshoot voltage) [mV]	70	200	70	200
tOvS_Max (Max Overshoot time duration) [us]	10	30	10	30

Table 51-7. Processor VR Design Values

Parameter	Vcc	Vcc _{GT}	VCCSA
CFL H 42 45W			
IPL2 [A]	60	25	10
IccMax current 10 ms max	Refer to the EDS for the IccMax numbers		
IccMax_App current	85% of IccMax	NA	
di (IccMax transient) [A]	69	26	3
di (IccMax_App transient)	IccMax_App di = IccMax_App - (IccMax - IccMax di)	NA	
dt (ns) (Slew time for the di step) (Note 3)	65	65	200
CFL H 62 45W			
IPL2 [A]	80	25	10
IccMax current 10 ms max	Refer to the EDS for the IccMax numbers		
IccMax_App current	85% of IccMax	NA	
di (IccMax transient) [A]	91	24	3
di (IccMax_App transient)	IccMax_App di = IccMax_App - (IccMax - IccMax di)	NA	

**Table 51-7. Processor VR Design Values**

Parameter	Vcc	Vcc _{GT}	VCCSA
dt (ns) (Slew time for the di step) (Note 3)	65	65	200
CFL H 82 45W			
IPL2 [A]	86	25	10
IccMax current 10 ms max	Refer to the EDS for the IccMax numbers		
IccMax_App current	85% of IccMax	NA	
di (IccMax transient) [A]	110	24	3
di (IccMax_App transient)	IccMax_App di = IccMax_App - (IccMax - IccMax di)	NA	
dt (ns) (Slew time for the di step) (Note 3)	65	65	200

1. All references to "TDC" in this document refer to PL2 current events. PL2 is a temporary event whose duration will be determined by the thermal capability of both the platform thermal solution and VR design.
2. IccMax_APP is not a spec. It is a characterization of limited samples using limited set of benchmarks under default PL1 and PL2 conditions. It aims to show more realistic current envelope that can be exceeded.
3. Simulated at processor motherboard pads. This parameter is not tested.
4. The time durations given here are for VR design only.
5. If using Psys, Intel recommends sizing the VR's thermal solution to support the domain's equivalent PL2 max TDC currents. By continually monitoring the platform's total power dissipation, Psys optimizes the AC adapter's PsysPL2 power capability, maximizing PL2 power delivered to the CPU(e.g. PL2 max operation) when rest-of-platform power headroom exists allows. Note: PsysPL2 is the sum of PL2 and ROP as measured at the power input. As ROP is reduced PL2 may increase, PsysPL2 remaining constant.
6. The SET VR TDC CONFIG mailbox register in the BIOS assumes a default tau of 1ms.

51.4 Voltage Regulator Requirements

Notes:

1. The Tolerance requirements have to be met at the package ball if the sense location is not on package. Additional decoupling may have to be added to meet the tolerance if the sense location is far away from the ball.
2. For VRs that implement Low Power mode (LPM) through a dedicated pin, the T_{LPM_EXIT} defines the minimum and maximum time allowed from LPM exit as measured from LPM L' H transition to the active voltage reached, regardless of the duration of the LPM signal L pulse width.
3. For VRs that implement Low Power Mode (LPM) through the ENABLE pin, the T_{EN} defines the maximum time allowed from IC_ENABLE to Vout (nom), regardless of the duration of the ENABLE (low) pulse width.
4. The Platform Power Sequencing Specification (PSS) Chapter in the Platform Design Guide (PDG) has additional requirements and the PSS specs supersede any requirements listed in the PDG.

**Table 51-8. Electrical Requirements for VCCIO VR**

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
V_{NOM}	Default voltage		0.95 LPM-0 V		V	Output voltage fixed on platform Refer to EDS for the required voltage level for a given CPU SKU.
Tolerance	Output Voltage Tolerance	-50		50	mV	DC+AC+ripple, DC to 1MHz For all VSEL settings in VCCIOCNT.
T_{LPM_EXIT}	Low Power Mode exit Latency	10		240	us	If VCCIO is turn off in C10(either through controller LPM pin or ENABLE pin. Time from CPU C10 GATE# de-assertion to VCCIO voltage stable
T_{EN}	Turn on delay	0.0085	3	5	ms	For start-up
SR	Voltage ramp slew rate			90	mV/us	
I_{STDBY}	Standby Current		1		mA	

Table 51-9. Electrical Requirements for V1.05A VR

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Output Requirement						
V_{NOM}	Default voltage		1.05		V	
Tolerance	Output Voltage Tolerance	-5		5	%	DC+AC+ripple, DC to 1MHz
I_{STDBY}	Standby Current		2		mA	

Table 51-10. Electrical Requirements for VTT VR

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Output Requirement						
V_{NOM}	Default voltage		VDDQ/2		V	VTT output voltage must track VDDQ
Tolerance	Output Voltage Tolerance	-5		5	%	DC+AC+ripple, DC to 1MHz
$I_{Trasient}$	Trasient Load Step			1.2	A	-600mA to 600mA for decoupling design

Note:

The voltage specification requirements are measured on VTT line as near as possible to the termination resistor with an oscilloscope with 3 x CLK bandwidth, 1.5pF maximum probe capacitance, and 1MΩ minimum impedance. The maximum length of ground wire on the probe should be less than 5mm. Ensure external noise from the system is not coupled into the oscilloscope probe. Or use differential probe between VTT and GND. All VTT net need to be measured separately.

**Table 51-11. Electrical Requirements for VDDQ VR**

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Output Requirement						
V_{NOM}	Default voltage		1.2		V	For DDR4
Tolerance	Output Voltage Tolerance	-5		5	%	DC+AC+ripple, DC to 1MHz
I_{STDBY}	Standby Current		8		mA	

Table 51-12. Electrical Requirements for V3.3_DSWVR

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Output Requirement						
V_{NOM}	Default voltage		3.3		V	
Tolerance	Output Voltage Tolerance	-5		5	%	DC+AC+ripple, DC to 1MHz
I_{STDBY}	Standby Current		5.3		mA	

Table 51-13. Electrical Requirements for V5A VR

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Output Requirement						
V_{NOM}	Default voltage		5.0		V	
Tolerance	Output Voltage Tolerance	-5		5	%	DC+AC+ripple, DC to 1MHz
I_{STDBY}	Standby Current		1		mA	

Table 51-14. Electrical Requirements for V1.8A VR

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Output Requirement						
V_{NOM}	Default voltage		1.8		V	
Tolerance	Output Voltage Tolerance	-5		5	%	DC+AC+ripple, DC to 1MHz
I_{STDBY}	Standby Current		1		mA	

Table 51-15. Electrical Requirements for V2.5U VR

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Output Requirement						
V_{NOM}	Default voltage		2.5		V	

**Table 51-15. Electrical Requirements for V2.5U VR**

Symbol	Parameter	Min	Typ	Max	Unit	Notes/Conditions
Tolerance	Output Voltage Tolerance	-5		5	%	DC+AC+ripple, DC to 1MHz
I _{STDBY}	Standby Current		1		mA	

51.5 AC Adapter Considerations

To support Turbo performance as well as to provide more flexibility on the size and cost of the AC adapter, this section will cover the important aspects of adapter requirements and trade-offs.

51.5.1 Power Budgeting for AC Adapter

The adapter power rating is divided into the sustained power level and transient power level. The sustained power level is the maximum constant power that the adapter can supply to system. The transient power level is the maximum peak power that the adapter can supply within a given duration of time, usually in milliseconds.

The adapter power rating has to meet the power demand of system, which can be divided in to SoC power and rest-of-platform (ROP) power. For the system with Turbo, the sustained SoC power is PL2 and the peak SoC power is PL4.

Default and Extreme Power Limits (PL2, PL4) are now provided in the Coffee Lake H Platform Power Map Design Guide.

The ROP power is determined by the components other than SoC. The number of USB ports, the display module, the memory module, etc., significantly impact on the ROP power level. As described in the Psys [Section 51.7](#), the Psys feature can monitor the ROP power in real-time. If Psys is not available, the designer has to estimate the typical ROP power level (P_{ROP_typ}) and the worst case maximum ROP power level (P_{ROP_MAX}) in order to size the adapter.

51.5.2 Transient Power Requirement for Turbo

The selection of charger PD architecture is going to affect the transient power requirements on the AC adapter in order to adequately support Turbo operation. The duration of transient power level depends on how long the battery takes to start providing power.

51.5.3 Sustained Power Requirement at Dead Battery Level

For the system with either Hybrid Power Boost (HPB) or NVDC charger, the sustained power requirement of the adapter can be estimated based on the scenario of a dead battery when the battery doesn't have enough charge to power the system and the AC adapter has to provide all the power. Intel recommends the Dynamic Battery Power Technology (DBPT) to better determine the battery power capability in real-time. See [Section 51.8](#) on battery and fuel gauge system for details.



P_{SYS} , the platform power monitoring and control feature on Coffee Lake can be used to maintain a desired P_{SYSPL2} level where the overly conservative estimation of ROP power can be reduced. Instead of using the worst case maximum ROP power level to estimate the sustained power level for AC adapter, the pre-defined P_{SYSPL2} can be used.

Table 51-16. Sustained and Transient Power Levels with different PD Architectures

Charger Type	Adapter Supplemented by Battery	Sustained Power Level with Dead Battery	Transient Power Level	Transient Power Level with Dead Battery Level
Traditional	No	Without P_{SYS} : PL2 + P_{ROP_MAX} With P_{SYS} : P_{SYSPL2}	Up to 10ms: PL4+ P_{ROP_MAX}	Up to 10ms: PL4+ P_{ROP_MAX}
Hybrid Power Boost (HPB)	Yes		Up to 1.5ms: PL4+ P_{ROP_MAX}	
NVDC	Yes		Same as sustained power level	

Note: The above power loading levels have to be divided by the conversion efficiency to get the final adapter output power levels. The P_{SYSPL} and PL values need to be updated regularly as the power capability of adapter and battery changes. In "CFL Turbo and Thermal Power Management Guide for Core™ based Processors", the flow chart and equations are provided to calculate P_{SYSPL} and PL values based on adapter power capability and battery power capability (DBPT) for 4 design options; NVDC with P_{SYS} , NVDC without P_{SYS} , HPB with P_{SYS} , and HPB without P_{SYS} .

51.5.4 Psys and Other Considerations for Using Smaller AC Adapter

There are some cases where a smaller adapter with lower sustained power level can be used for better portability or lower adapter cost. However, there will be impacts on the dead battery operation, Turbo performance, and charging time.

If an AC adapter with sustained power level less than PL2 + P_{ROP_MAX} , it is recommended to have P_{SYSPL2} enabled and set P_{SYSPL2} to the sustained power rating of AC adapter. However, there could be performance impact if the sustained power of adapter is much less than the PL2 + P_{ROP_MAX} and user loaded the ROP power close to the worst case maximum. Here is an example.

For example, in a system with PL2 of 25W, PL4 of 46W, P_{ROP_MAX} of 15W, and conversion efficiency of 90%, the sustained power level of adapter can be calculated with the following equation. An adapter with a sustained power rating of 45W is recommended for this system.

$$P_{sustained} = (PL2 + P_{ROP_MAX}) / \text{Efficiency}$$

However, if a smaller adapter with 30W sustained power rating is used with this system, without P_{SYS} , the PL2 will have to be reduced down to 12W, which is even less than PL1 of 15W. In this scenario, both PL2 and PL1 have to be reduced to 12W when the battery is dead. If the system has a traditional charger, the PL2 and PL1 have to be reduced to 12W no matter if the battery is dead or not as long as the adapter is connected.

On the other hand, if the system has P_{SYS} enabled, the performance will be managed to keep the P_{SYSPL2} at 30W. If the rest of platform power is lowered to 10W, the SoC will have 17W of power budget and the performance should be better than the case without P_{SYS} .



With a smaller adapter, the charging time from 0% to 80% state of charge will likely be impacted. However, the actual charging time impacts depends on many other factors besides the sustained power rating of adapter, such as the power state of system, battery size, constant current charging rate. As the sustained power rating is reduced, the power available for charging is going to be reduced first.

51.5.5

Protection Mechanisms

The electrical protection mechanisms cover the following two scenarios: the magnitude of system peak power exceeds the adapter transient power limit, and the duration of system peak power event exceeds the duration of adapter transient capability.

In the event when system peak power might exceed the adapter transient power limit, the over-current-protection (OCP) is designed to sense the adapter current and trigger PROCHOT# if the over-current condition is met. For the discrete implementation, refer to "Battery Voltage Droop & Brick Over Current Protection Circuit Design" doc# 509511. There are chargers with integrated PROCHOT# circuit available as well.

However, after PROCHOT# is triggered, the SoC frequency is going to be reduced to the minimum causing significant performance loss. So instead of hitting PROCHOT#, the system EC may reduce PL4 as a preemptive measure if an under-sized adapter is connected.

51.6

Battery Charging System

This section reviews battery charger topologies used in mobile system designs.

During CPU Turbo Boost periods, the system may overload the input power source. The battery charge controller shall be capable of operating in hybrid power mode where the battery discharges to supplement the DC input power. There are two types of charger topologies capable of doing this:

1. Hybrid Power Boost (HPB) battery charger
2. Narrow VDC (NVDC) battery charger

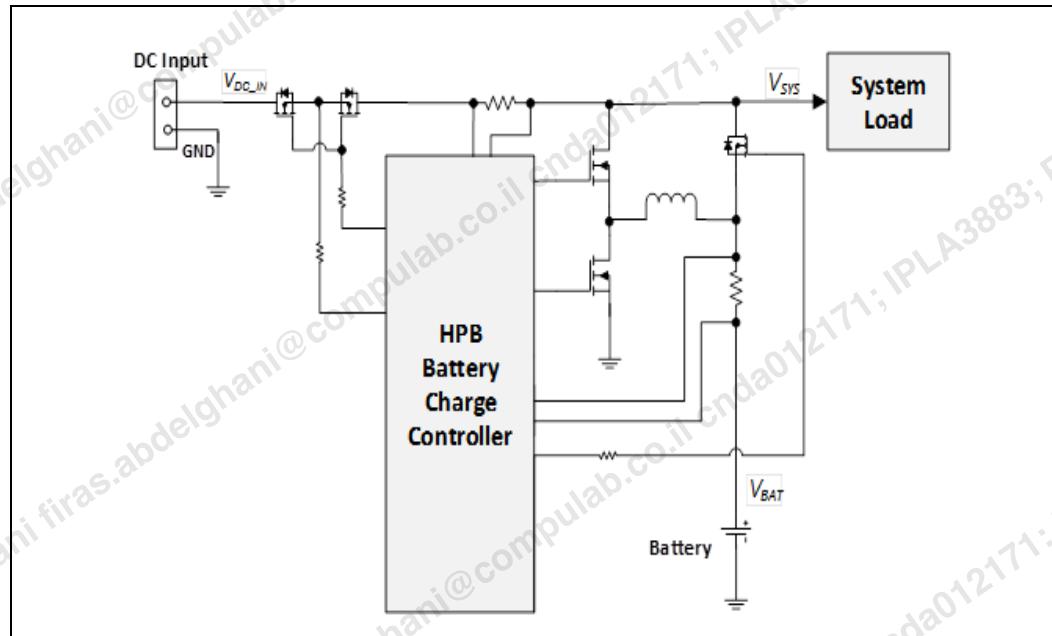
51.6.1

Hybrid Power Boost (HPB) Battery Charger

In the Hybrid Power Boost configuration, the synchronous buck converter runs as a normal buck converter when the adapter provides power to the system and is charging the battery. When the adapter power is not sufficient, the synchronous buck converter runs in reverse to boost the battery voltage to around 20V. Thus the battery supplements the adapter whenever the adapter power is not sufficient. This requires no circuit changes from a traditional adapter. The change is required in the control circuit (the Battery charger controller).

The advantage of this system over a traditional charger is that the battery is able to assist the adapter during turbo workloads. This system has the disadvantage that the light load efficiency is pretty low as it is difficult to achieve high light load efficiency at high input voltage.

Figure 51-4. Hybrid Power Boost (HPB) Battery Charger



51.6.2 Narrow VDC (NVDC) Battery Charger

Figure 51-5. Narrow VDC (NVDC) Battery Charger

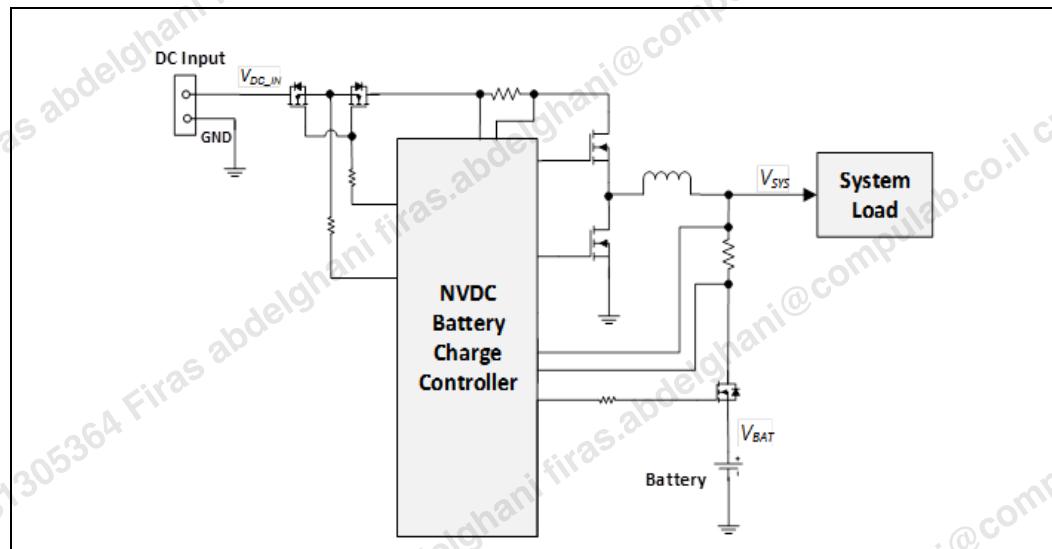


Figure above shows the Narrow VDC (NVDC) topology. Here, the system bus (V_{SYS}) is not connected directly to the adapter. It is connected to the output of the buck converter. Hence, NVDC operates only as a buck converter, both when NVDC charges the battery and when the battery supplements the adapter and provides power to the system. NVDC implementation reduces the switch-over period between the charging

mode and the hybrid power mode. NVDC implementation allows the system to minimize the period of overloading the input power source when CPU is in Turbo Boost mode.

The advantage of using the NVDC system is that the overall system efficiency is better compared to the Hybrid Power Boost charger. The system can be designed for a smaller voltage rating since the system has a lower V_{in} . The disadvantage is that the charger components' size and power dissipation increases.

51.6.3 Benefits and Trade-Offs

Table 51-17. Benefits and Trade-offs of the Different Chargers

PD Architecture	Turbo support	Advantages	Limits
Traditional charger	No. Rely on adapter or battery	More common for system with less dynamic load.	VRs with large range of input voltage are less efficient at light load. Adapter has to be sized to supply peak system power for 10ms.
Hybrid power boost	Yes	Higher input voltage is more suitable to larger system with large power consumption.	VRs with large range of input voltage are less efficient at light load. Adapter has to supply peak system power for 1ms.
NVDC with 2S battery	Yes	Design optimized with Lower input voltage has better light load efficiency. FETs can be optimized for lower input voltage and VRs can be smaller and faster.	Charger's components (FET/ Inductor) size increase (small for Ultrabook™) Additional power dissipation localized to charger area

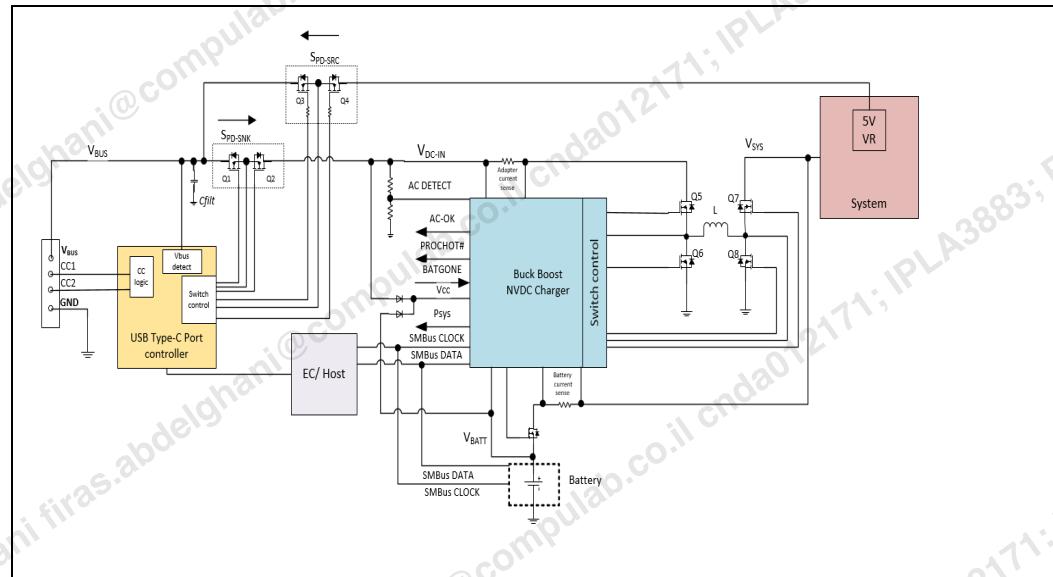
Section 51.7 describes P_{SYS} , the protection mechanism for the input power sources.

51.6.4 Chargers Supporting 5V-20V USB Charging

USB Power Delivery usage models suggest the following operating modes on the USB charging port:

1. System battery providing power to USB ports (5V, up to 3A OUT)
2. 5V USB adapter providing power to the system(5V, up to 3A IN)
3. USB PD Charger to provide power to the system and battery (9V, 15V, 20V up to 3A or 5A IN)

In order to support all of these charging modes, the Buck Boost charger provides a simple, cost effective and space saving solution.

Figure 51-6. Detailed View of USB-PD Subsystem**Figure 51-7. Modes of Operation**

OPERATION							
Mode	Power Flow	Topology	Q1	Q2	Q3	Q4	
1 Battery Powering USB (e.g. mouse, KB, HD, charging phone/tablet; V _{batt} >V _{usb})	Batt→USB	Buck CV	Control FET	Sync Diode	ON	OFF	
2 Generic USB Charging Battery (V _{usb} <V _{batt} , i.e. V _{usb} =5V)	Batt←USB	Boost CC/CV	Sync Diode	Control FET	ON	OFF	
3 USB PD Charging Battery + Sourcing System (V _{usb} >V _{batt} , i.e. V _{usb} =12V/20V)	Batt←USB	Buck CC/CV	ON	OFF	Control FET	Sync Diode	
4 Battery Operation w/ No USB (No adapter or USB plugged in)	None	Short Protection	OFF	OFF	OFF	OFF	

51.6.4.1 Features Desired in Buck Boost Charger

1. Adapter voltages to be supported: 3.8V - 20V sustained
2. Battery configurations to supported: 2S - 4S (5.6V - 17.4V)
3. Two level programmable input current limit (sustained and peak)
4. Default input current limit programmable by hardware pin
5. Platform power monitoring (P_{SYS})
6. PROCHOT# - System voltage, Input current, Battery discharge current (and input voltage)
7. Low power mode during battery only Sx/ S0ix mode (consume <1.5mW)
8. SMBus or I2C compatible

For detailed Buck Boost charger requirements, refer to Buck Boost Charger Specification – Power Supply Design Guide RDC#561998



51.6.4.2 Design Considerations for 5V VBUS Operation

It is important to consider the following factors when using a buck boost charger on the platform:

1. With a 5V USB input, the inrush current on the system bus should be limited when the charger and system rails are enabled. This is especially important under a dead battery power on scenario.
2. The maximum resistance from the USB VBUS to the input of the charger should be <50-60mΩ in order to operate at 5V.
3. Dead battery power on sequence with a port controller needs to take into account a way to power on the TCPM/ EC and meeting the pSnkStdby requirement. If the TCPM is powered using the V3.3A rail, care should be taken to ensure that inrush current does not exceed the default current limit set on the charger.

51.7 Platform Power Monitoring And Control (P_{SYS})

For thermal control, previous platforms had the ability to throttle the processor speed to reduce SoC power consumption and keep the average power dissipation of the SoC package within defined limits. Coffee Lake Platform has added the ability to monitor and control the average power the platform is consuming and throttle the SoC to keep the overall platform power dissipation within defined limits. The new platform power level limits are useful to keep the average power of the platform within the power ratings of input power sources, voltage regulators and batteries. The feature of measuring total platform system power is termed P_{SYS} or System Input Power Monitor.

51.7.1 Benefits

The P_{SYS} function provides a measure of the instantaneous power consumption of the entire platform. The PCode in the SoC uses the measured platform power to adjust SoC performance to keep the average platform power within desired limits. The measured platform power is also available to the Embedded Controller (EC) via the PECI interface and to software and firmware applications via MSR registers. Some systems may also have the EC sample the analog P_{SYS} signal after the resistor to avoid latency. The following is a list of benefits and features available with the SoC varying performance to keep the average platform power within limits and the ability of other software agents to read the platform power:

1. Real time monitoring of the platform power enhances the ability to support turbo mode when the platform is being powered by the battery only.
2. The average power of the platform can be kept within the average power rating of the input power source even if peak platform power temporarily exceeds the rated power of the input power source. This allows smaller wattage input power sources (battery and AC adapter) to power a platform that has high peak power requirements by keeping the average power demand within limits of the input power sources.
3. The platform power demand can also be adjusted to keep the average platform power and thus the average platform temperature under desired levels.
4. Previous thermal solutions measured the power to the SoC and used an estimate of the power the rest of the platform (ROP) was consuming to determine power budgets. Some potential performance gains are not realized in the cases where the actual ROP power consumption is less than the estimate. For these circumstances,

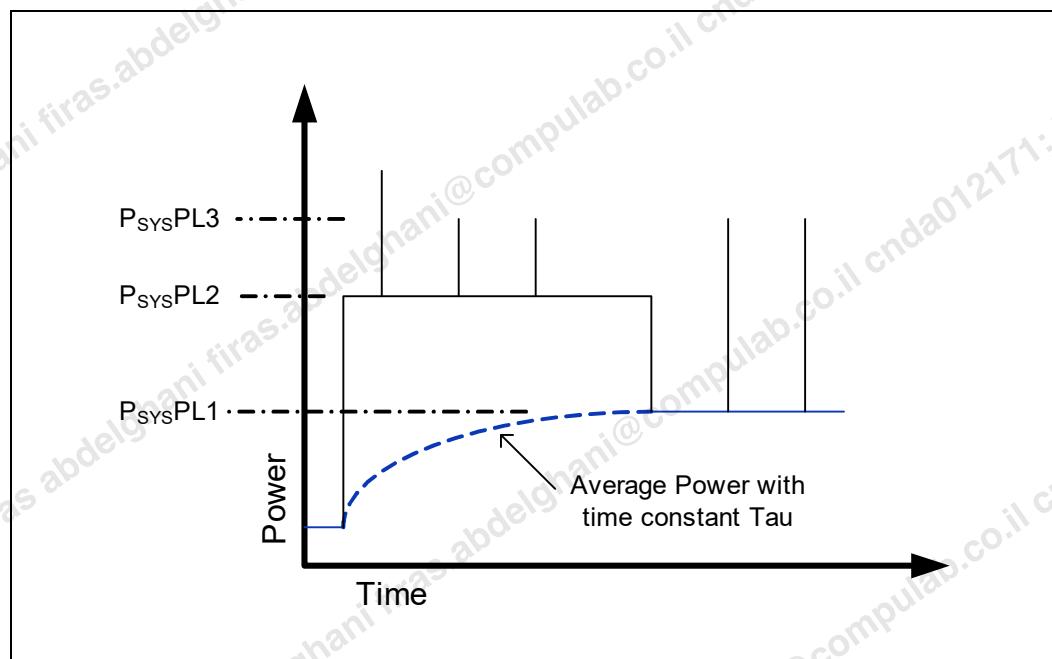
using the actual platform power consumption (P_{SYS}) will provide an increase in turbo performance.

- The platform instantaneous power consumption can be monitored by firmware and software to provide applications that provide power monitoring and feedback to the user.

51.7.2 Theory Of Operation

The P_{SYS} feature function parallels the package level power monitoring features. Registers hold defined power limits for the platform. The new power limits are defined as P_{SYSPL1} , Tau , P_{SYSPL2} and P_{SYSPL3} . Figure below shows the relationship between the different power levels.

Figure 51-8. Relationship Between Platform Power Levels



The P_{SYSPL1} level is the long term sustainable power limit of the platform. This can be the rated power of the adapter, the discharge rate of a battery, the power capability of the platform or a combination of all of these. P_{SYSPL1} has a time constant (Tau) associated with it. P_{SYSPL2} is a power level that the platform is allowed to have for a temporary time. For example, a battery can be discharged at a higher rate for a short period of time as long as the average discharge is equal to P_{SYSPL1} . Shorter period but higher power limits can also be supported up to the P_{SYSPL3} level, for example, discharging the battery at 4C for less than 10ms and a 9% duty cycle. The SoC will adjust power consumption to drive the average power consumption to the P_{SYSPL1} level over a long period of time which is greater than Tau .

51.7.3 Hardware Ingredients

The P_{SYS} feature requires some hardware components for implementation in order for the platform to measure the power it is consuming. Figure 51-9 and Figure 51-10 show typical implementations of the P_{SYS} feature. The platform must be able to monitor the

power going to the platform. In a battery powered device, the power going to the system is the power coming from the input adapter, plus any power the battery is providing. Using a battery charger with a power monitoring function makes the most sense since the battery charger monitors both of these pieces of information already. Several battery chargers with a power monitoring feature have been enabled to support P_{SYS} on Coffee Lake platforms.

Figure 51-9. HPB Battery Charger with P_{SYS} Implementation

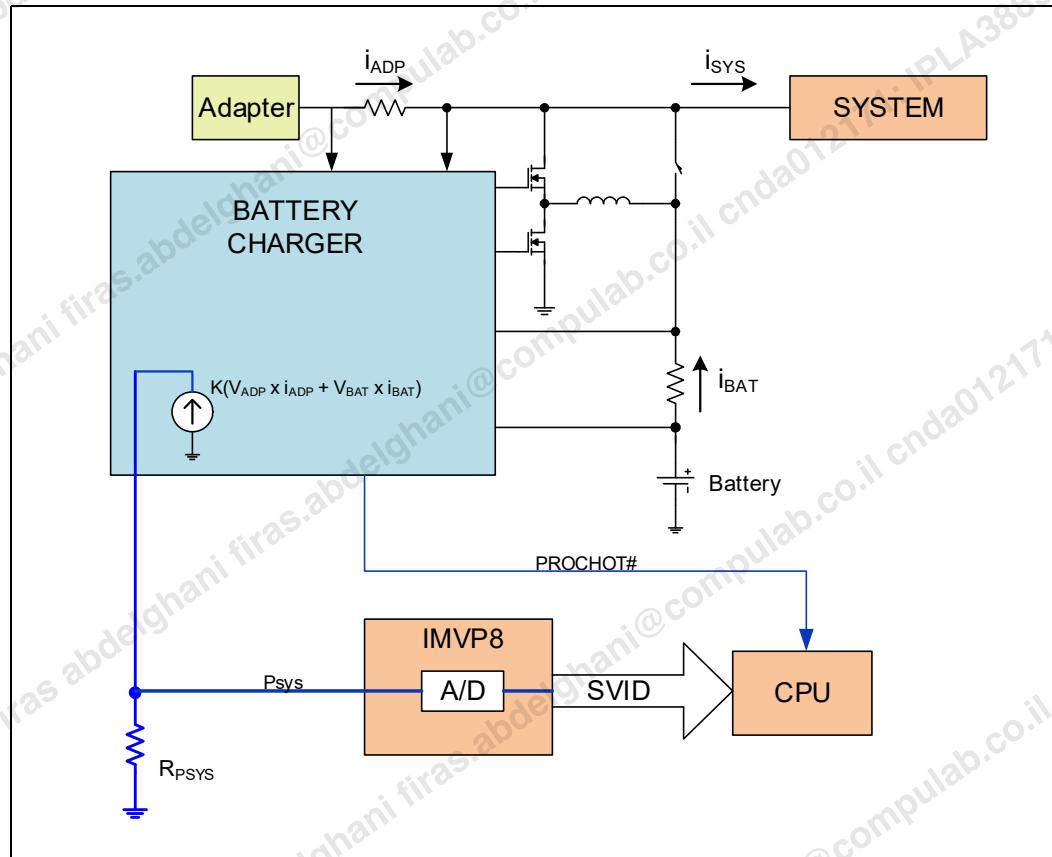
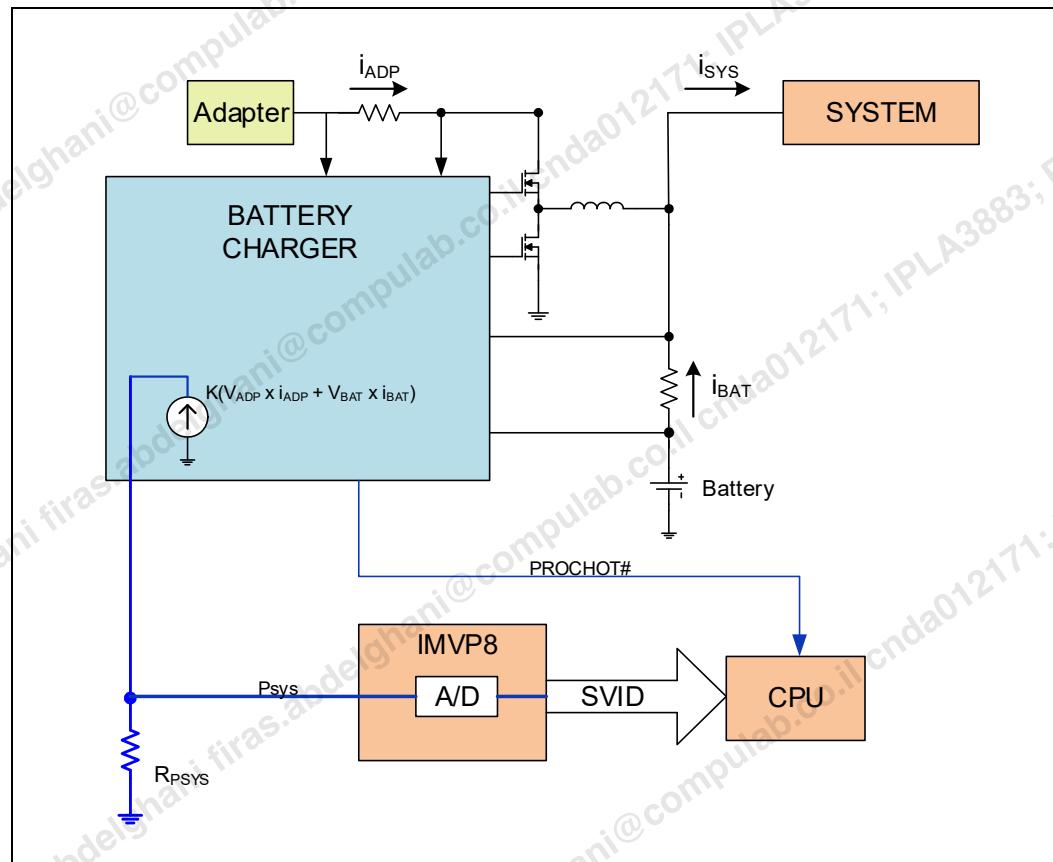


Figure 51-10. NVDC Battery Charger with P_{SYS} Implementation



The battery charger provides a current output that is proportional to the power being delivered to the platform (from the brick, battery or both). A shunt resistor is used to convert this current output to a voltage output and to scale the voltage to the full scale input voltage range of an analog to digital converter. The platform uses the SVID interface to read the power data. The measured platform power is provided in SVID register 0Dh, location 1Bh. An 8 bit A/D converter in the IMVP8 controller is used to convert the power monitoring information. The processor then reads the power measurements via SVID from SVID address 0Dh, location 1Bh. See the 'Serial VID (SVID) Protocol' specification and the 'IMVP8 PWM VR' specification for specifics on the IMVP8 and SVID.

The PROCHOT# signal shown in Figure 51-9 is a signal that indicates to the CPU that a platform event has occurred that requires the immediate power reduction by the processor. The PROCHOT# signal provides a faster mechanism for power reduction than P_{SYS} and is used to protect the input sources against instantaneous power events rather than the average power.

PROCHOT# can be triggered by multiple sources in the platform. PROCHOT# typically is asserted by the battery charger under the following conditions:

1. The amount of adapter current exceeds an upper threshold.
2. The amount of battery discharge current exceeds an upper threshold.
3. The battery voltage falls below a lower threshold.



If the PROCHOT# levels are programmable then the levels should be set to protect the input source. For example, the PROCHOT# for the adapter current level should be programmed to at the current the adapter can provide without damage such as a fuse blowing.

If PSYS is used to protect the input power source then specific information about the input power source must be relayed to the platform. The platform must know the power capability of the input power source which can be a wall adapter, wireless system charger, battery, USB-PD port, USB-BC port or any other of a variety of sources. Typically, the input power source capability will be determined by the EC on the platform.

51.7.4 Software/Firmware Ingredients

The new PSYS Monitoring and Control Parameters are:

PSYS is the value provided to the processor PCU from the platform through SVID quantifying the total platform power load. This value shares the name of the feature.

PsysP_{MAX} is the maximum power the platform is capable of drawing. It is the sum of PL4 plus the Rest of Platform power.

PsysPL1 is the targeted total platform power level to which the PCU's platform power monitoring and control will manage over time. The value is provided by the system.

PsysPL2 is the highest power level to which Psys will be allowed to go on a temporary basis while there is budget to do so (analogous to RAPL's PL2). The value is provided by the system.

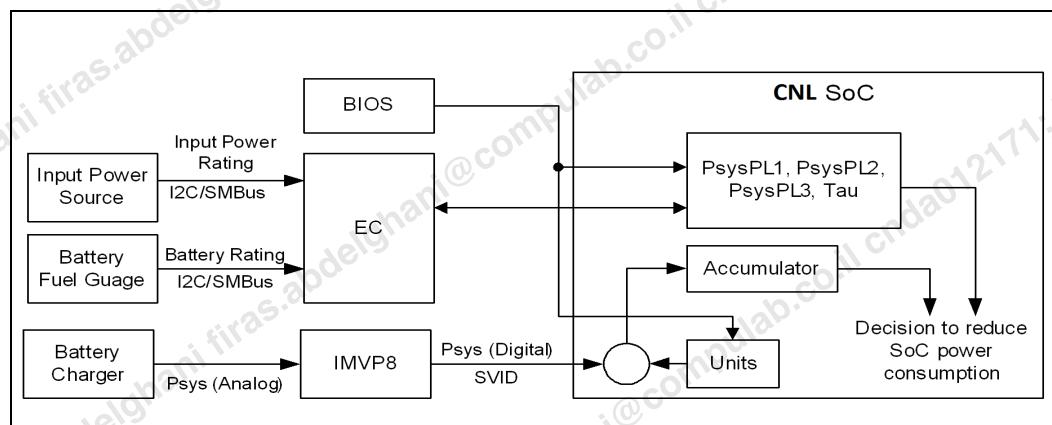
Tau is the time window which roughly characterizes the time scale under which Psys monitoring and control manage to the target PsysPL1 value. The value is provided by the system.

PsysPL3 is the same limit value/feature as the legacy PL3. PsysPL3 triggers control such that Psys power level events exceeding it are limited to a small duty-cycle percent on time; e.g., 10%; notwithstanding power spiking events caused by another component on the platform. No change in function. PsysPL3 limit value uses the platform level power (Psys) as a basis for decisions instead of package power.

The MSR registers and bit definitions pertinent to Psys functionality can be found in the Coffee Lake BIOS Guide (Refer to table below).

Table 51-18. Access Availability of the Various P_{SYS} Configuration Parameters

Parameter	Description	Access (Addresses Defined in HAS)			
		MSR	MMIO	PECI	BIOSMB
P _{SYSPL1}	Platform average power target	RW	N	RW	N/A
P _{SYSPL2}	Turbo/Momentary average platform power target	RW	N	RW	N/A
P _{SYSPL3}	Duty cycle controlled average platform power target	RW	N	RW	N/A
P _{SYSTau}	PL1/PL2 Time Scale	RW	N	RW	N/A
Enable	PC Monitor/Control On/Off	RW	N	RW	N/A
P _{SYSValue}	Actual value of P _{SYS}	RO	N	RO	N/A

Figure 51-11. Information Sources and Flow Diagram

51.7.5 Configuration

The P_{SYS} feature can co-exist with other thermal and power management features found on the platform.

At power on, BIOS must initialize the P_{SYS} power limit registers (P_{SYS_PMAX} and P_{SYSPLx}) to reflect the basic configuration of the platform. During run-time, the EC or other software/firmware agents can update the P_{SYSPLx} values as platform conditions change such as a new input power source being plugged in.

51.7.6 Implementation of P_{SYS}

P_{SYS} is enabled by:

1. Clearing bits: [30] SVID Presence, and [31] Platform IMON (P_{SYS}) Disable. Clear these at Flash Address FCPUSBA + 004h (default Flash Address 304h). Refer to the SPI Programming Guide.
2. Enable P_{SYS} functionality in your charger. Usually done through your EC.
3. Program the P_{SYS_PMAX} value to PL4+ROP_{MAX} (Rest Of Platform) power. Refer to the BIOS Specification.
4. Select a value for R_{PSYS} as shown in Section 51.7.6.1.

The $P_{SYS_P_{MAX}}$ value is the scale that the processor uses to interpret the P_{SYS} values read from the IMVP8 controller. There is no specific $P_{SYS_P_{MAX}}$ which is correct.

1. Use a $P_{SYS_P_{MAX}}$ value that is large enough to cover the most power the platform could possibly draw.
2. Use a $P_{SYS_P_{MAX}}$ value which is small enough to provide the granularity appropriate for the platform.

51.7.6.1 Determining the value of R_{PSYS}

R_{PSYS} is sized to develop the P_{SYS} current from the charger so the voltage input to the IMVP8 ADC will reflect the value of $P_{SYS_P_{MAX}}$ as FFh.

R_{PSYS} should be placed near the IMVP controller.

[Figure 51-9](#), here are some examples where:

$P_{SYS_P_{MAX}}$ = the max power for a platform, PL4 + ROP_{MAX}. Programmed as above.

$ADC\ V_{REF}$ = the full-scale voltage on the IMVP8 P_{SYS} pin. An ADC converts this voltage level to FFh. Different for each IMVP8 controller.

I_{PSYS} = the μ Amps/Watt of the P_{SYS} signal from the charger. A typical value is 1 μ A/W, but your charger may vary.

The formula for determining the value of R_{PSYS} is:

$$R_{PSYS} = ADC\ V_{REF} / (I_{PSYS} * P_{SYS_P_{MAX}})$$

Table 51-19. R_{PSYS} Examples

$P_{SYS_P_{MAX}}$	I_{PSYS}	$ADC\ V_{REF}$	R_{PSYS}
35W	1 μ A/W	1.2V	34.3K Ω
95W	2 μ A/W	3.3V	17.4K Ω
175W	1 μ A/W	1.6V	9.1K Ω

51.8 Battery and Fuel Gauging System

This section suggests system architecture for the U-Line battery and fuel gauging systems. [Section 51.8.1](#) on Dynamic Battery Power Technology provides information on how Turbo can be performed during discharge, given a two series Li pack configuration, providing for maximum performance.

We have adopted a cost / functionality strategy for the U-line. We see the market being divided into three segments (shown below) which can be identified by differences in their battery and fuel gauging system.

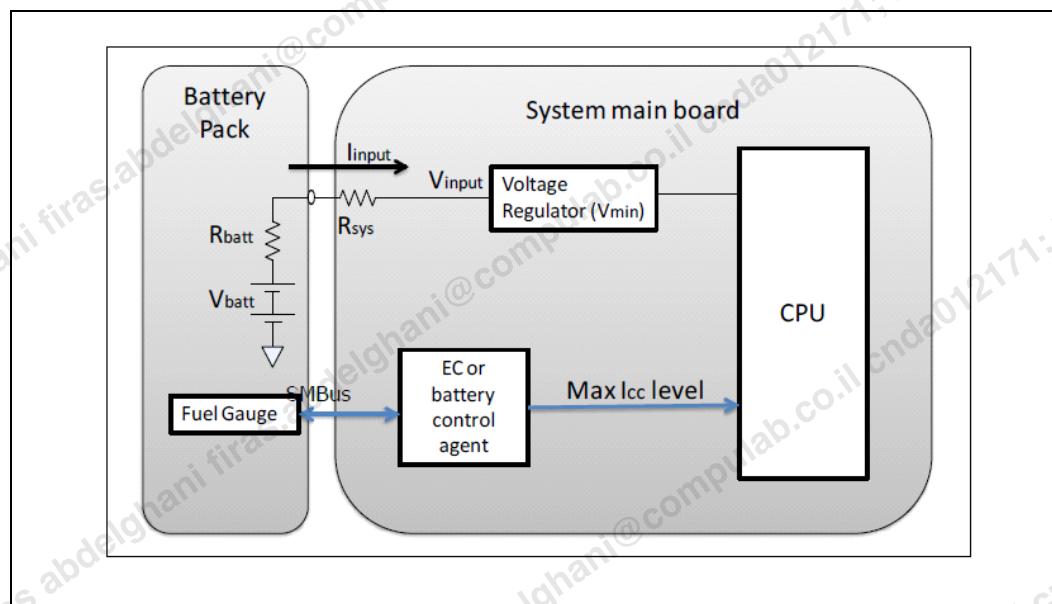
1. Volume Segment: Battery and fuel gauging system designed to meet nominal battery runtime at nominal cost targets. Fuel gauging system provides nominal accuracy. Approaching full SoC performance.
2. Premium Segment: Battery and fuel gauging system designed to meet maximum battery life. Fuel gauging system provides best accuracy, and supports Dynamic Battery Power Technology. Full SoC performance

3. Value Segment: Reduced battery life to meet cost target. Fuel gauging system may sacrifice accuracy to save cost. Nominal SoC performance.

51.8.1 Dynamic Battery Power Technology

Figure below shows the top level architecture of Intel DBPT version 2 (Dynamic Battery Power Technology). The input voltage of system regulator, V_{input} , is lower than the open circuit voltage of battery cells, V_{batt} . The voltage drop depends on the load current, I_{input} , and the total parasitic resistance from cells to regulator, R_{batt} and R_{sys} .

Figure 51-12.DBPT Top Level Block Diagram



Where R_{batt} includes both cell resistance and parasitic resistance due to the cell interconnect, sense resistor, FET, fuse, connector of battery pack. R_{sys} includes the resistance of power/ground metal, sense resistor, FET, and other parasitic resistance on the system main board.

In order to prevent V_{input} from violating the required minimum system input voltage, V_{min} , I_{input} has to be adjusted according to the level of V_{batt} as the battery is discharged, as the impedance of the battery changes with state of charge, temperature, and age.

DBPT adds commands to the SMBus command set, so that the fuel gauge reports the maximum power the pack can support for a Turbo pulse. The pack takes into account, R_{sys} , R_{batt} , and V_{min} when reporting what maximum power the pack can support. The system is then able to implement an algorithm so that the combination of SoC and other power sources stay within this allowed power envelope, so that an under-voltage condition does not occur.

There are two versions of DBPT. The first version defines an SMBus command `MaxPeakPower()` that reports the ability of a battery pack to deliver power for up to 10ms. This is useful for setting the maximum PL4 value for the SoC, while making sure the battery voltage droop, combined with losses between the cells and voltage regulator are allowed for. DBPT version 2 implements all the features of DBPT, and adds



the additional SMBus command SusPeakPower() which reports the ability of a battery pack to deliver power for up to 10s. This is useful for setting the maximum PL2 value for the SoC, while again allowing for voltage droop and power loss between the battery and voltage regulator.

For further information on DBPT, refer to the following documents:

- Intel Dynamic Battery Power Technology v2, SMBus Implementation Specification RDC#498853
- Intel Dynamic Battery Power Technology (Intel DBPT and DBPT v2) Implementation Considerations RDC#564428.

Without DBPT, the pack voltage must be chosen so that under load the pack voltage cannot fall below Vmin. Ways to achieve this are to choose cell counts of 3 or more series Li cells. An alternative is to allow Turbo events on discharge, only to a predetermined critical threshold based on state of charge of the pack. The issue with this approach is that the impedance of the battery changes based on age and temperature, and the solution involves reducing SoC performance in an overly conservative way. DBPT allows for the SoC to perform optimally, at any given battery impedance.

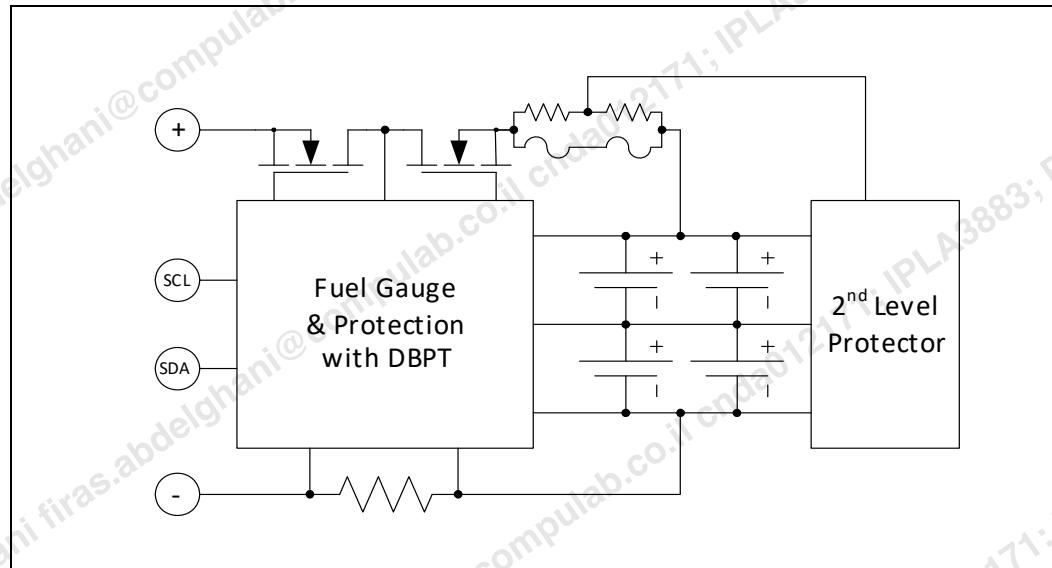
51.8.2 Fuel Gauging

By choosing between the following fuel gauging types, it is possible to tailor the fuel gauging solution cost, by trading off functionality. The following choices of fuel gauging solution are ordered below, starting with the most accurate, highest featured. As the list continues the features are reduced, along with the cost.

51.8.2.1 In-Pack SMBus Fuel Gauge with DBPT

This solution for in-pack fuel gauging which supports DBPT provides for greatest runtime by providing the greatest fuel gauging accuracy. This solution also provides the greatest performance, as it allows for Turbo operation over the entire discharge cycle. Solutions which provide support for 2-4 series connected Li based cells are present in the market, from the two premier fuel gauging suppliers.

Figure 51-13. Block Diagram of In-Pack Fuel Gauge with DBPT

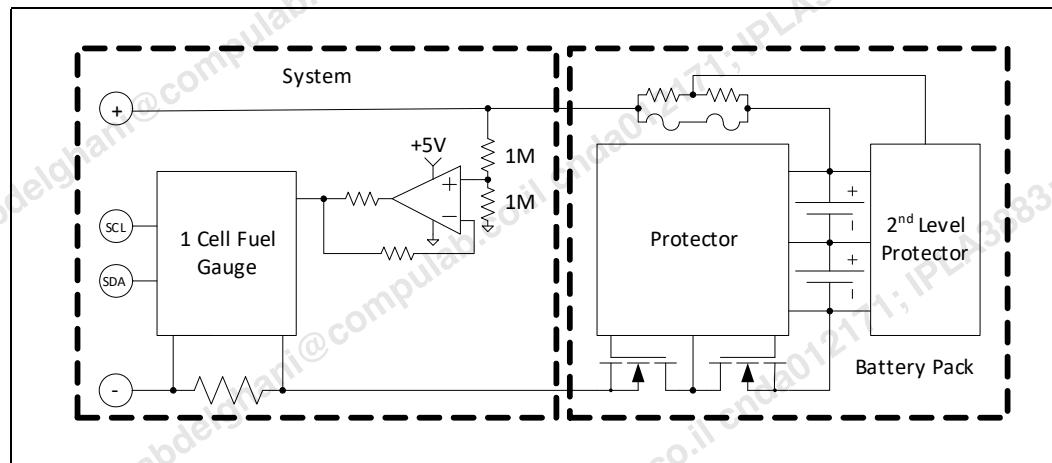


51.8.2.2 In-Pack SMBus Fuel Gauge without DBPT

This solution for in-pack fuel gauging provides for greatest runtime by providing the greatest fuel gauging accuracy. As this solution lacks support for DBPT, this solution is well suited to configurations of 3-4 series connected Li based cells, which support Turbo during discharge. With the higher cell count, typically the dropout concerns that might impact a two series configuration are not present. This solution is also a viable choice for a Li two series system, which will not Turbo during discharge. The block diagram of this system is identical to the In-pack SMBus Fuel Gauge with DBPT, as the only change is a fuel gauge that lacks the DBPT support, typically available at a lower price point.

51.8.2.3 In-system Fuel Gauge without DBPT

This solution for In-system fuel gauging provides for adequate fuel gauging accuracy. This solution also foregoes support for DBPT. The solution utilizes the selection of fuel gauging parts aimed at the cost competitive one cell fuel gauging market. As the SoC solutions require 5V rails, this solution uses an Op-Amp to divide the pack voltage of a 2 series Li pack configuration in half, and supply this precision divided voltage to the fuel gauge solution designed to handle one series cell. A typical block diagram of such a system is shown below.

Figure 51-14. Block Diagram of 1S Fuel Gauge with 2S Pack

Note:

In such a system the Op-Amp and the divider resistors should be chosen to provide a very accurate division ratio, as inaccuracy in this division will directly affect fuel gauging accuracy. This means selection of an Op-Amp with a very low input offset voltage. In addition a matched set of divider resistors, or high precision resistors should be evaluated for their effect upon accuracy. Note that the Op-Amp will not be required to swing to the power or ground rails if powered by a 5V rail, so cost can be saved by choosing a low power, low input offset amplifier, which does not provide rail to rail output swing. The bandwidth of the amplifier is of some concern, but a bandwidth of 200kHz should be adequate to give good results. It is suggested to consult the fuel gauge manufacturer to determine what bandwidth their gauging solution requires.

In Windows* solutions, a reporting of current is required by the operating system, so be sure to choose a single cell gauging solution which reports current for such systems. Other operating systems may not require reporting of current. Single cell gauging solutions which monitor only voltage, can provide a bit lower price point while typically giving up a couple percent of accuracy.

51.8.3

Battery Pack Size and Configuration

The battery pack is typically size to meet goals for runtime and peak power. In order to achieve the highest performance for the processor, please specify the battery based on guidelines for power capability of the pack from [Table 51-20](#).

Table 51-20. Battery Discharge Capability Recommendations

Recommended peak duration	10ms	100 sec	Constant discharge
Recommended Max Discharging Power Level if P_{SYS} is not used	$PL4 + P_{ROP_MAX}$	$PL2 + P_{ROP_MAX}$	$PL1 + P_{ROP_MAX}$
Recommended Max Discharging Power Level if P_{SYS} is used	$PL4 + P_{ROP_MAX}$	$P_{SYS}PL2$	$P_{SYS}PL1$
Peak Duration with $PL3/P_{SYS}PL3$	configurable down to 2ms ¹	NA	NA
Duty Cycle with $PL3/P_{SYS}PL3$	configurable down to 4% ¹	NA	NA

Note:

- Refer to *CFL Turbo and Thermal Power Management Guide for Core™ based processors RDC#566828*



Once the power capabilities to support a performance level are decided, a choice of pack configuration remains.

The choice is often between two series and three series configurations of Li based cells. Two series configurations result in higher currents, when compared to a three series configuration, for equivalent system power consumption. This would normally tend toward choosing the higher voltage solution, as power losses increase with the square of the current. The other factor is that with a lower voltage range, the DC/DC converter can typically be optimized for a better overall efficiency, which tends to favor the two series solution. Another factor to consider, is that a three series configuration will likely not have issues with reaching low voltages during Turbo events, where a two series configuration may reach low voltages under load, and require support of DBPT to manage this. For the lower power consumption systems in this line, an NVDC charger configured for two series cells seems to achieve the greatest system efficiency. For higher power consumption systems in this line, a three series cell configuration will achieve the greatest system efficiency. The tradeoff between the two approaches can be gauged, by looking at the I^2R losses throughout the power system in the two approaches.

A trade-off that is often overlooked is that of fuel gauging accuracy, and pack cost. If we think of battery pack cost in terms of \$/Wh (dollars per watt-hour), then any inaccuracy in the fuel gauge can be expressed as a cost in dollars, for a given pack size. For example, given a 50Wh pack, and a cell cost of \$0.40/Wh, the cost of cells would be \$20. When choosing between a 6% accurate fuel gauge, and a 1% accurate fuel gauge, it makes sense to look at the cost of that potentially lost capacity, when looking at the price difference between the gauges. With a difference of 5% in accuracy, and a cell cost of \$20, the 1% accurate gauge could be \$1 more expensive ($\$20 * 5\% = \1), and still offer better performance. The 6% accurate gauge would need to increase the cell cost by \$1 to allow for the potentially decreased runtime due to gauge performance. In addition the more accurate gauge will offer a solution that is smaller and lighter, as the pack capacity that is purchased is fully used, rather than just sized up to allow for fuel gauge inaccuracy.

51.9 Dynamic Fast Charging Technology-DFCT

Fast charging is becoming a feature sought out by many customers. There are several challenges to providing fast charging within a system.

First is the potential impact to the size of the AC Adapter needed to provide this fast charge capability. To charge faster requires more power during at least a portion of the charge cycle. If the requirement is to provide faster charging while the system is in a lightly loaded or off state, it may be possible to fast charge without increasing the AC Adapter wattage. If fast charge is required under all power states, then more AC adapter wattage is likely required.

The cells in the battery must be capable of fast charging. There is increased power dissipation in the charger circuitry while fast charging, so either additional thermal handling capability must be present, or the charge rate must be controlled based upon the thermal environment.

There are several vendors that provide algorithms designed to fast charge "standard" cells, while promising to preserve the cycle life. Previously the method used to report and control fast charging was proprietary to each vendor, which made implementation of solutions complex, and limits reuse when moving between vendors.



DFCT addresses many of these concerns. It provides a standardized set of SMBus commands that are used to define the fast charge. The algorithm resides within the battery pack or fuel gauge in the system, as this subsystem has the best understanding of the cells. Allowing for multiple vendors with the same commands stimulates innovation, and allows for moving between different vendors with various algorithms, without needing new code for the embedded controller. DFCT can be used with Dynamic Platform Thermal Framework, DPTF, to provide fast charging in a way that allows control of the thermal issues within the system.

For further information on DFCT, refer to the following documents:

- Intel Dynamic Fast Charging Technology, SMBus Implementation Specification RDC#564466
- Implementing Fast Charging with Intel Dynamic Fast Charging Technology (Intel DFCT) RDC#564842.



52 Flexible Instrumented Platform (FIP) Design

Power instrumentation is vital in measuring and analyzing sub-subsystem power to enable full-system power optimization; Power Sequencing and Low speed signal test for system functionality test/verification and debug. Current system instrumentation technique involves connecting sense resistors on the board to the Data Acquisition Device (DAQ) manually for system power optimization and system functionality verification/debug. This method has several pitfalls and carries risks such as tedious manual re-work, quality concerns, and potential board damage. In this paper we introduce a new technique of power instrumentation called the Flexible Instrumentation Platform (FIP) design. The FIP design offers many advantages over existing methods such as one-time effort requiring no manual rework, no risk of shipping damage and shorter setup time.

52.1 Background

Sense resistors and Power/Electrical test access are typically not part of the production design. Hence power instrumentation and low speed electrical signal test access technique involve manually connecting sense resistors on the board and using wires connected to a pod on the DAQ for measuring current, voltage and power consumption as well as to use a Scope/Digital multi-meter for low speed signal test.

As depicted in [Figure 52-1](#) and [Figure 52-2](#), existing instrumentation introduces several challenges:

- Manual rework time: instrumentation takes three days best case for the whole board with one dedicated labor. Also this rework has to be done for each board.
- Quality concern: potential lack of quality in soldering can affect power measurement accuracy.
- Potential risk: Board damage caused by rework at limited board and SOC sample stages that may be gating product launch without tuning to extend battery life to meet/exceed target.
- Portability Issues: the instrumented platforms connected to pods are sensitive to damage such as wires pulling pads off. This affects ability to move or transport instrumented boards without damage.
- Setup time: connecting individual wires to DAQ takes time and depending on the number of rails/ channels, it can take half a day or more.

Additionally, customers that do take the time to add power instrumentation to their designs do not include consistent accurate labeling to the wires. Also they tend to hot glue the sense resistor location making identification very difficult, sometimes impossible. The FIP implementation proposed here reduces the requirement for power measurement teams to become intimately familiar with the customer design for setup, therefore enabling full focus on software power optimization.

Figure 52-1. System Instrumentation Block Diagram

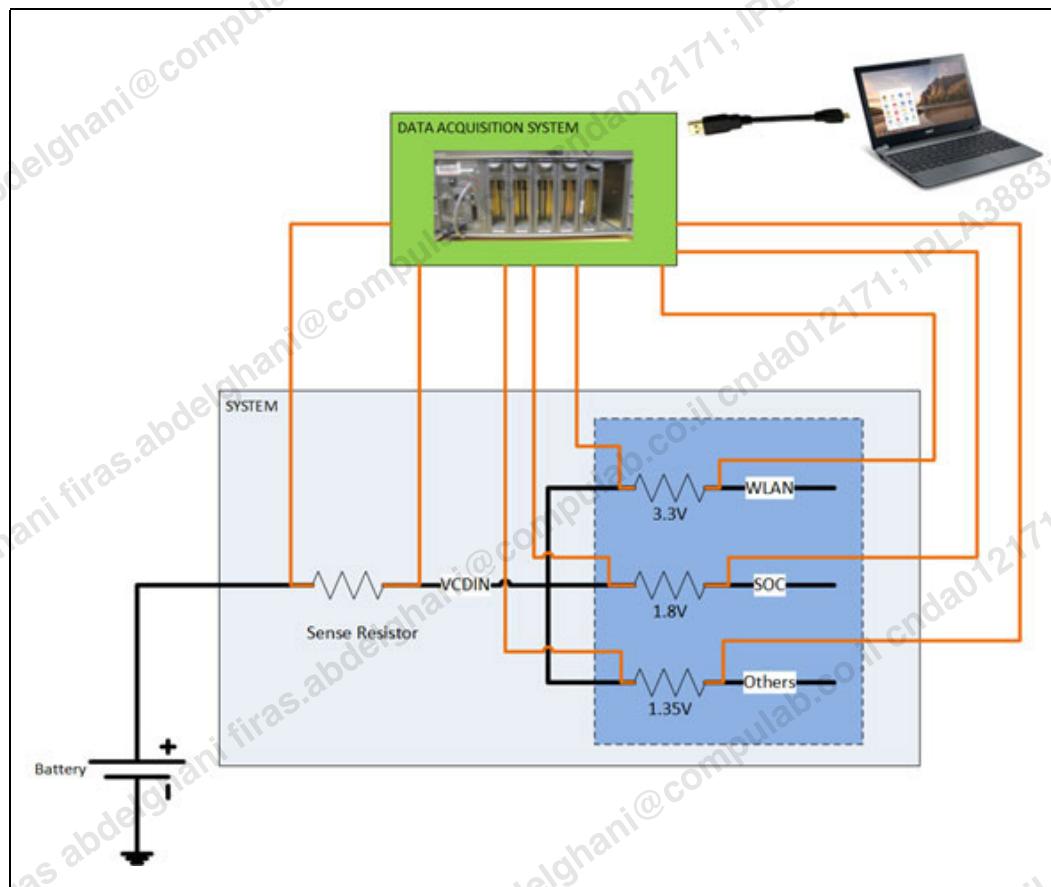
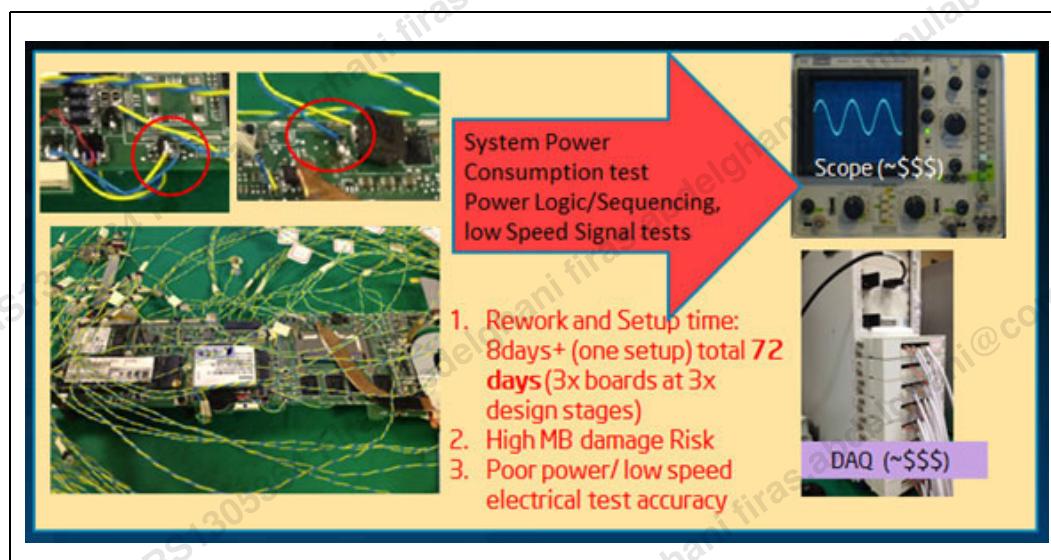


Figure 52-2. Power Instrumentation Setup





52.2 Overview

This section introduces a new instrumentation design proposal. FIP design minimizes the risk introduced by the current instrumentation techniques by adding extra sense layers on the PCB and routing the instrumented wires to an extended PCB space with a Flexible male DuPont connector. The board can then be connected via a Flexible DuPont cable to the DAQ for power measurements and scope for low speed electrical signal measurements. Figure below shows an overview of the FIP design.

FIP involves adding the following components:

- Four extra PCB layers
- Industry flexible DuPont header connector
- Flexible extended PCB space sense resistors
- FIP trace routing to the edge
- FIP (Via in Pad) sense resistors
- FIP Vias
- Inner layer impedance coupon (be added for power rail <900mA)

Figure 52-4 shows the difference between FIP and non-FIP boards and Figure 52-5 and Figure 52-6 show the layout for top/bottom and inner layers' current sense resistors calibration (for power consumption measurement accuracy) FIP design.

Figure 52-3. Flexible Instrumentation Overview

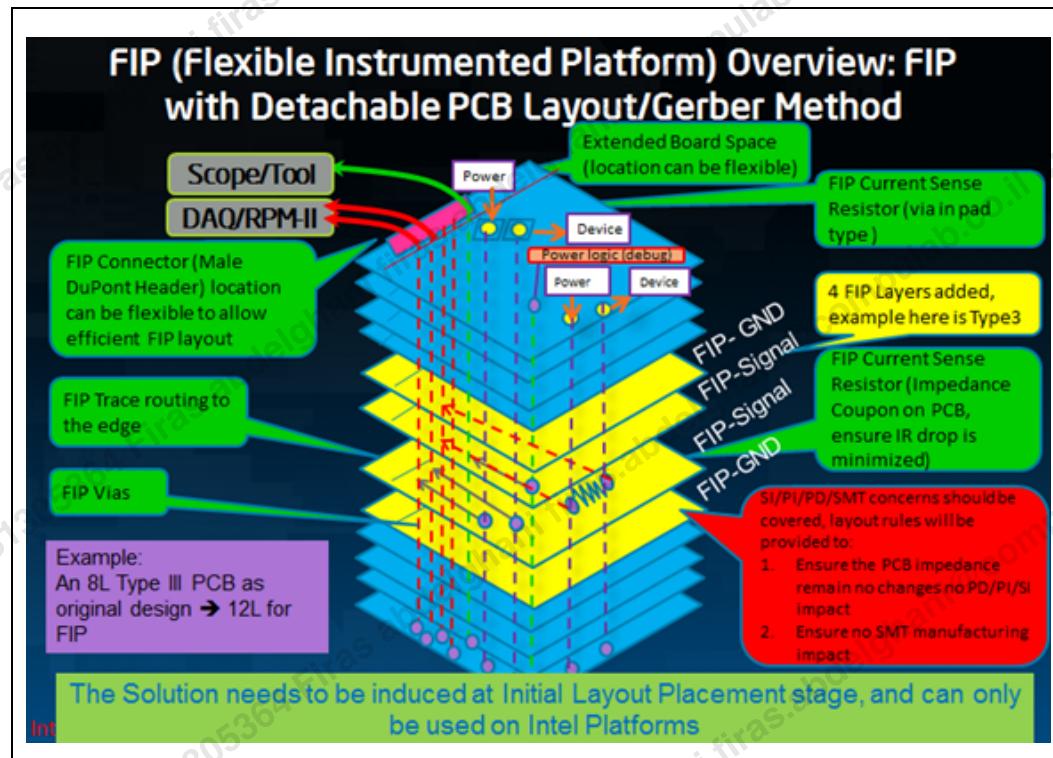


Figure 52-4. FIP Board versus Non-FIP Board

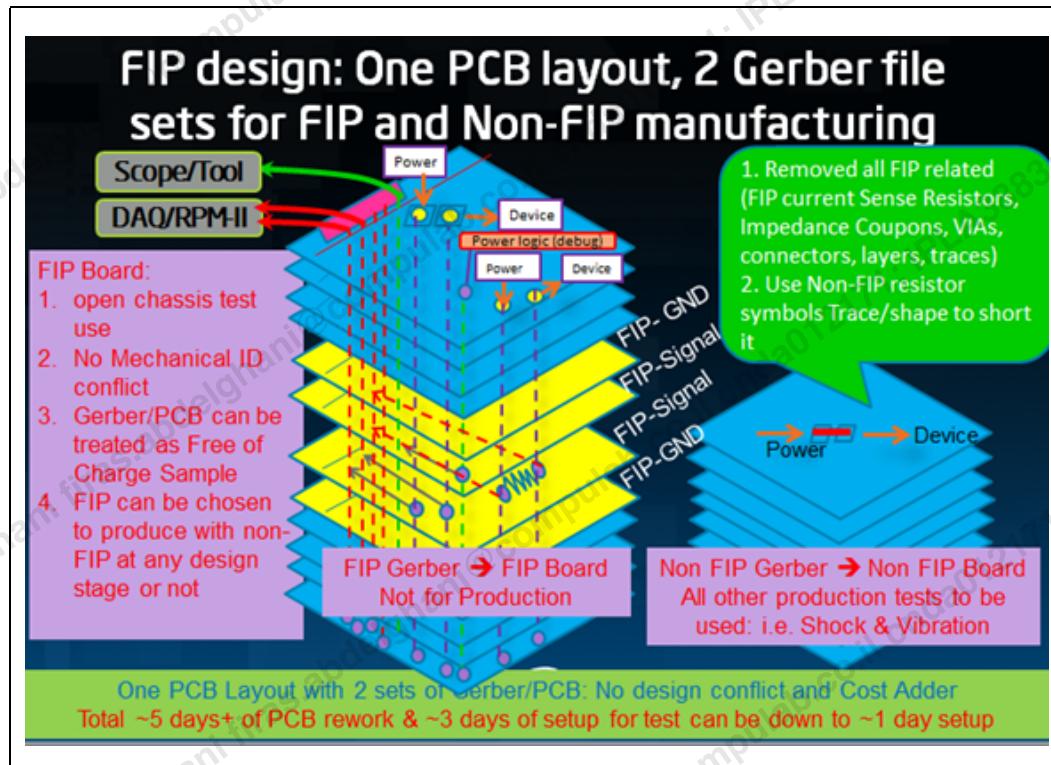


Figure 52-5. Layout for Inner Layout Current Sense Resistors (impedance coupon) Calibration

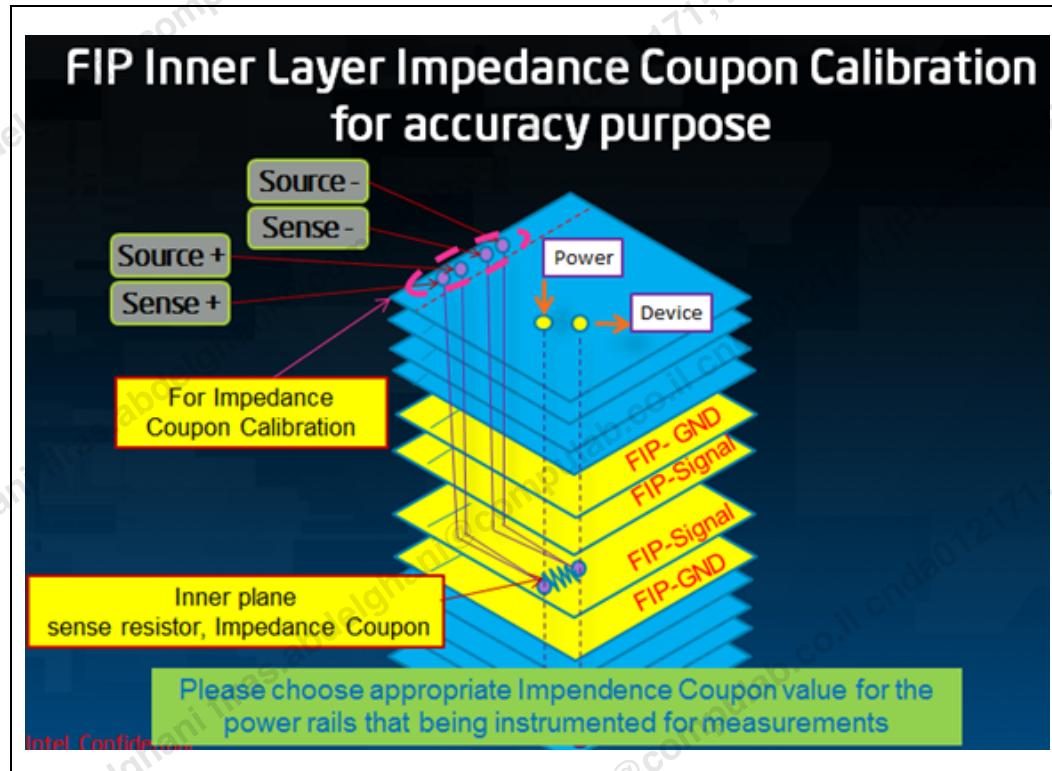
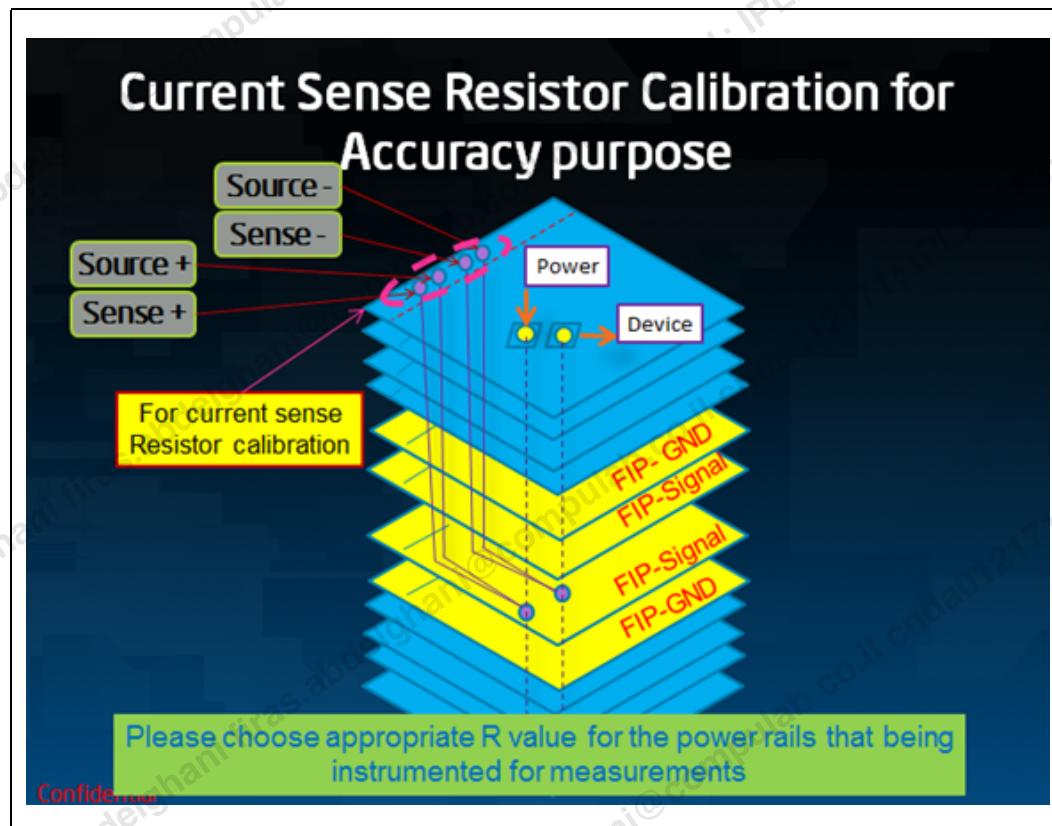


Figure 52-6. Layout for Current Sense Resistors Calibration for Top and Bottom Layers

52.3 FIP Design Details

This solution is FIP a design with detachable layout solution with all test trace layout to connector for connection to the DAQ/ scope including below. Total setup time is approximately less than one day for complete system power measurements and risk of damaging the board via reworks or setup is eliminated.

1. Complete system power rail instrumentation.
2. Low speed electrical signal test access.

52.3.1 FIP Details and Steps

The solution design involves a detachable PCB layout and Gerber method. This package involves designing one PCB layout and generating 2 Gerber files for manufacturing 2 PCBs, one as non-FIP, and the other as a FIP design. The non-FIP design will not have any current sense resistors, and can be ~1USD/piece saving. The FIP PCB can be attached/ removed to the board at any design stage without impact to the original board design. There are no additional design costs nor any rework resource costs associated with addition of power instrumentation to the non-FIP designs. We also avoid the risk of damaging boards by manual rework at limited sample stages and risk of not able to fully debug/fine-tune system low power to extend battery life before product launch schedule.



The PCB design for the two different PCB types is given below:

1. Type3 PCB
2. HDI PCB

Both recommend to have VIP (Via in Pad) sense resistors: N Layer stackup vs. N+4 L (bigger board size to hold a connector). If the number of boards needed is within manufacturer's sample quantity, then there is a potential to not incur any additional costs as some manufacturer do not charge for samples.

1. The design steps for the FIP are:
2. Add 4x layer to core of the original design
3. Define the FIP symbol (Connectors, Current Sense Resistors, Impedance Coupon for inner layer)
4. PCB placement
5. Route System Traces and FIP traces
6. Generate FIP Gerber and Non-FIP Gerber

52.3.1.1 STEP 1: Add 4x Layer to Core of Original Design

The PCB stack-up solution is defined by consulting with the project SI and PI engineers. The FIP layers design should have the least impact to the system base design in terms of impedance control, signal ground/ power referencing especially on high speed I/O signals and should avoid cross talk. A PCB stack-up design proposal adding the 4x layer to the original design in [Table 52-1](#) shows a base design example and [Table 52-2](#) shows the SIP proposal for that base design.

Table 52-1. Base Design Proposal

Base Design			
Layer	Layer Thickness (in mm)		Signal
	Layer	Insulator	
L1	1.55	2.7	Signal
L2	0.6	4	GND
L3	0.6	4	Signal
L4	0.6	4	VCC
L5	0.6	4	Signal (only low speed signals will be routed here)/GND
L6	0.6	4	Signal
L7	0.6	2.7	GND
L8	1.55	-	Signal

**Table 52-1. Base Design Proposal**

Base Design			
	Total Thickness	32.1mm	

Table 52-2. FIP Design Proposal (with 4x Layer Addition)

Layer	SIP Design		
	Layer	Layer Thickness (in mm)	Signal
L1	1.55	2.7	Signal
L2	0.6	4	GND
L3	0.6	4	Signal
L4	0.6	4	VCC
L5	0.6	4	FIP -GND (connect to system ground as defined by the layout rules)
L6	0.6	4	FIP-S1
L7	0.6	4	FIP-S2
L8	1	-	FIP-GND (connect to the system ground as defined by the layout rules)
L9	0.6	4	Signal (only low speed signals will be routed here)
L10	0.6	4	Signal
L11	0.6	4	GND
L12	1.55	2.7	Signal
	Total Thickness	46.25mm	



52.3.1.2 STEP 2: Define FIP Symbols

Establish a layout symbol library for the FIP and define the FIP resistor symbol and non-FIP resistor symbol options. Figures below shows the FIP/ non-FIP symbol design.

Figure 52-7. FIP/non-FIP Symbol Design Examples-1

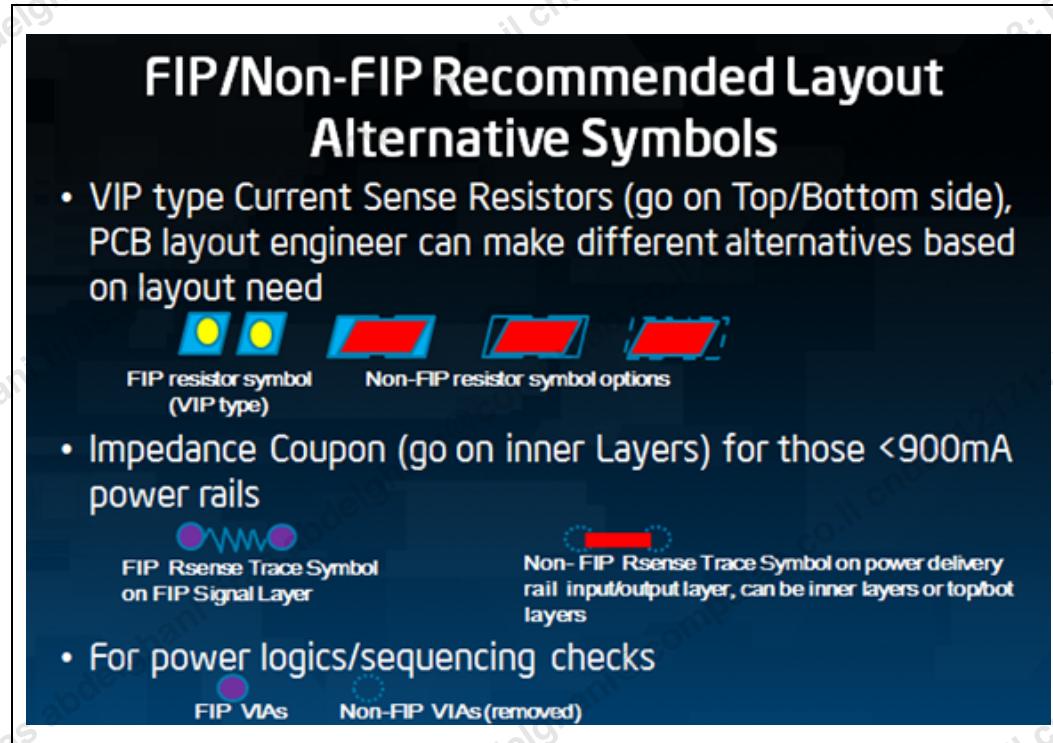
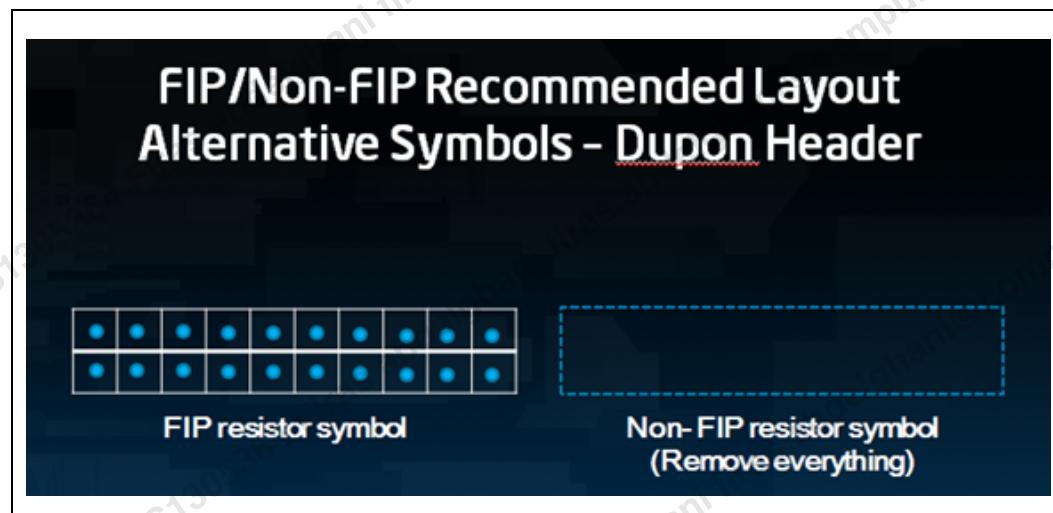


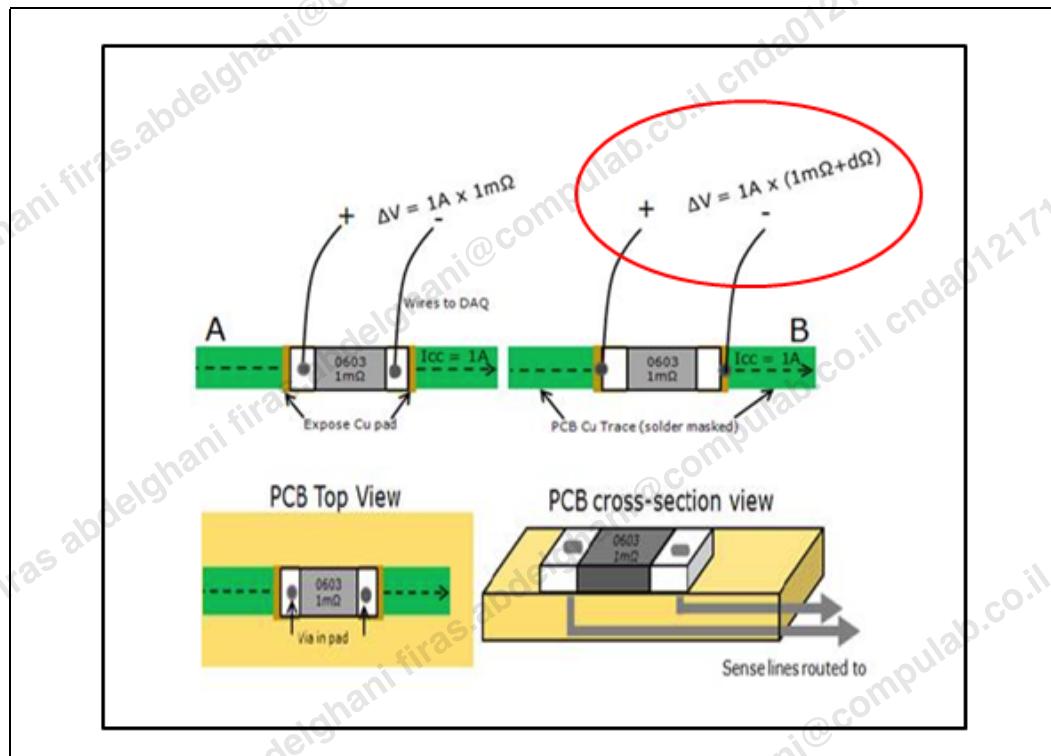
Figure 52-8. FIP/non-FIP Symbol Design Examples-2



52.3.1.3 STEP 3: PCB Placement

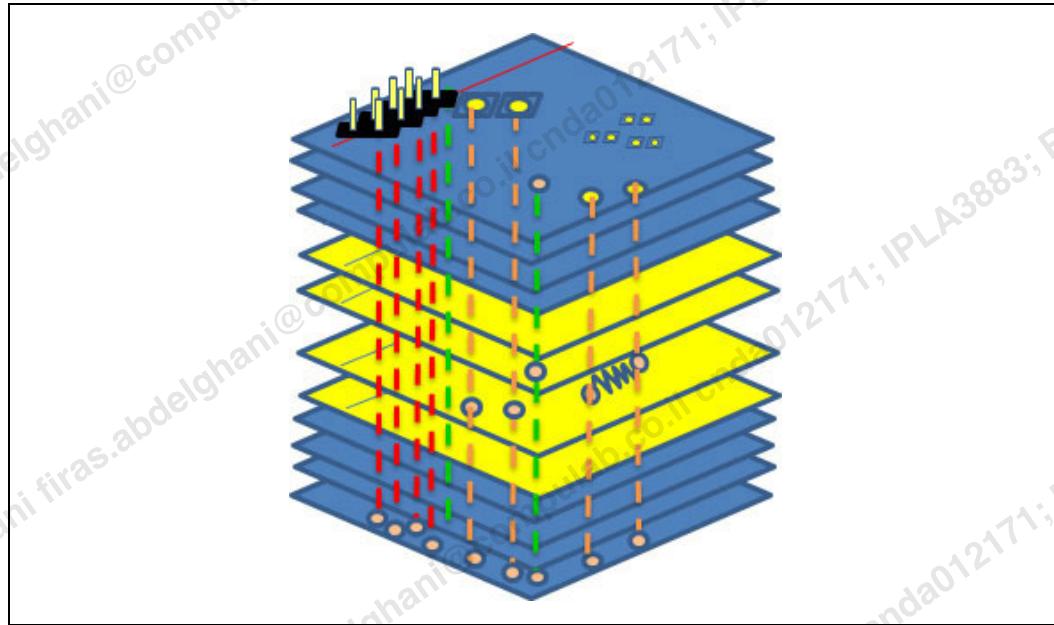
Secure the sense resistors with via in the PCB placement stage. Via creates a precise contact point between the wire and the sense resistor. The placement of any via on the FIP board is critical since a variation of via placement from one site to next will result in marginal variations in the total resistance used to measure the IR drop and current. This in turn results in discrepancies in the power measurement data that impacts the power data quality as shown in Figure below. Conclusion is, VIP sense resistors should be used as described in [Table 52-1](#) for library generation. Test vias alternative symbols should be generated for low speed signals for FIP and Non-FIP Gerbers.

Figure 52-9. Variations in IR Drop due to Via Placement



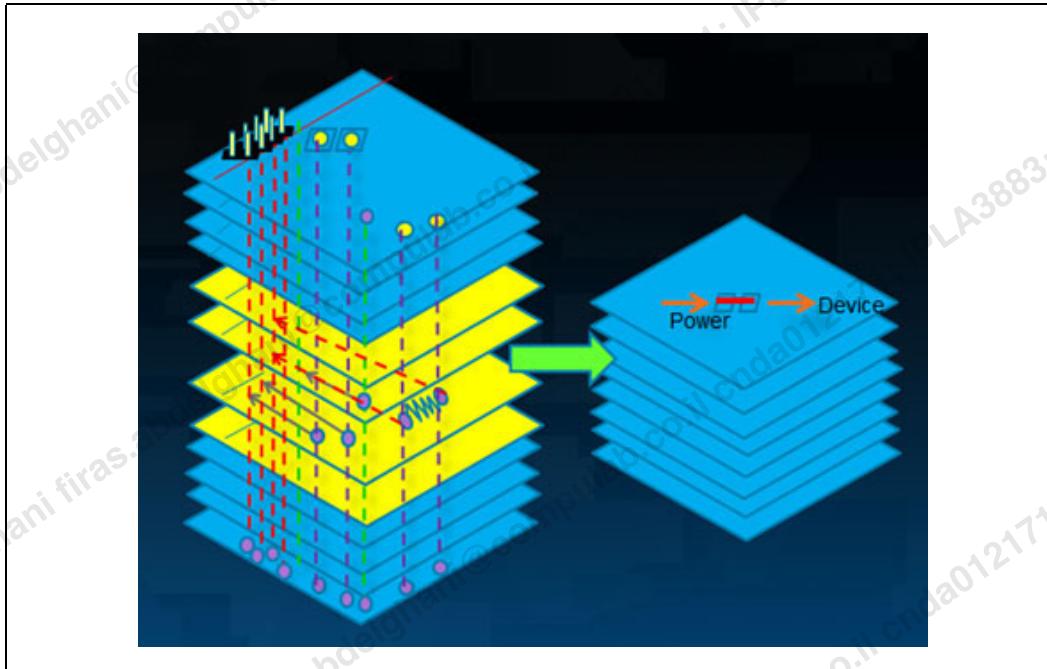
52.3.1.4 STEP 4: Route System and FIP Traces

Place the FIP resistors with VIP type and FIP Vias at placement stage and secure the space with VIAs (through Vias and/or Blind/Buried Vias), Route and complete the system traces prior routing the FIP traces. Figure below shows the steps.

Figure 52-10.PCB Placement

52.3.1.5 STEP 5: Generate FIP Gerber and Non-FIP Gerber

After routing the system traces and the FIP traces, the next step is to generate the FIP and non-FIP gerber. In the non-FIP gerber, remove all the FIP layers, FIP vias, FIP connector, F/IP traces, and replace the sense resistor symbol with the alternative symbol for short trace (refer Figure below) and remove the test vias for the non-FIP.

Figure 52-11.FIP and Non-FIP Gerber/PCB

52.4 DuPont Header Connector

A DuPont header on the flexible PCB layout space is a 2.54mm pitch connector. The pin count is not fixed but is determined by the FIP layout flexibility. If there is adequate layout space, a Flexible connector with clear pin map assignments can be placed on the board, and a Flexible cable can be used for saving time and effort during test setup. Flexible cable will also reduce the cost and will be easier for mass adoption across different engineering teams. [Figure 52-12](#) shows an example of DuPont header connector.

Figure 52-12.DuPont Header Connector

52.5

General Guidance for the FIP Solution

- Prepare schematics to generate two sets of net lists for layout to allow one PCB design and two sets of Gerber file generation.
- FIP schematics should include FIP attributes such as:
 - Current Sense resistors (using Via-in-Pad types with both vias connecting to the test pins of 2.54mm pitch DuPont Header connector), power logic test pads of 2.54mm pitch DuPont Head connector, and a GND-FIP (with short pairs of pads connecting to platform GND). The non-FIP schematics do not have FIP attributes included. Current sense resistors are defined as FIP resistors.
 - FIP resistor value/size need to consider the max current/wattage of the resistor can handle, and with high accuracy (1% tolerance or better) and recommend sense resistors remain on same layer with power delivery path from source to receiver
 - Define test signal with POS-FIP_PowerNetName for the power input side of sense resistor and Neg-FIP_PowerNetName and connect to FIP connector measurement pins.
 - Add FIP attribute to all the FIP traces.
 - Define all FIP resistors to have “No_Shape_Connect” property on via-inpad.
 - Define power logic signal test traces as FIP and route to the FIP connector defined PINs for Power Logic test.
 - Define the connector that power test points with positive signals on one side and negative signals on the other side.
- The PCB layout guidance are given below:
 - Add 4 extra layers to the center, use PCB copper weight recommendations: 1oz and define FIP layer (GND-Signal-Signal-GND) to be added to the layout placement stage, ensure system signals not falsely referenced to FIP ground. Have your PI/SI review to ensure no SI/PI concerns specifically on the defined stack-up with FIP, do SI/PI simulation as needed (such as if adding a capacitor is needed)



- Define power logic signal test traces as FIP and route to the FIP connector
- Define VIAs and Traces for Power Logic test with FIP attributes
- Define the DuPont headers that power test points with positive signals on one side and negative signals on the other side
- If there is no board space to hold DuPont header consult with mechanical designer to make two board outlines for FIP and non-FIP support, one for FIP (bigger one that holds DuPont header, while ensuring SMT process is compliant) and one for non-FIP
- If enlarging board size is a concern to go in chassis at design stage, set V-Cut from the extending edge or separate different PCB design with two sets of Gerber files for two sets of PCB (while impedance control is considered)
- Implement current sense resistors on both input and output of each VR. If impedance Coupons used in inner layer, used only on rails <900mA (consult with your SI/PI engineer ensure no SIP/PI concerns)
- All FIP measurements reference to FIP ground (all rails' ground connected together then connect to system ground), so only 2 points of voltages across sense resistors and 2 source signals (if calibration needs to be done) need to be laid out to the FIP connector (pin headers) unless your data acquisition has different requirements
- FIP traces for the power rails should be routed in a differential fashion, and the following rules apply:
 - FIP Voltage sense line layout rule (i.e. 1oz copper weight, if different, please recalculate below accordingly)
 - For power consumption test: routing on 2 inner layers between FIP_GND: Differential pair from VIP FIP sense resistors
 - For both power consumption and logic test: 5mm trace/4mm space/10mm between pairs min spacing, keep 15mm minimum spacing to other signal traces/vias; for any clock, high speed signals, keep away as far as possible, or recommend 20mm+ space
 - For impedance coupon FIP trace layout, as recommend only <900mA rails to use impedance coupon, use 10mm/4mm (if space allows, enlarge the distance) and 20mm+ space to other signals, if different copper weight is used, trace width should be calculated accordingly
 - NO || routing on adjacent layers (max allowed || routing less than 100mm)— NO routing under INDUCTORS /avoid switching node on Vreg)
 - FIP traces should avoid Hi-Speed Signal Routing areas
 - The FIP_GND reference planes should extend to the FIP Connector area, while other PWR/GND planes (from pre-existing layers) should be relieved at the GND areas so as not to reference the FIP connections
 - Use different net name for FIP ground and connect FIP ground to system ground with 3x Ohm resistors and 3x capacitors (place on 4 different places, such as 4 corners of PCB, and far from power switching source) to avoid other system signal faulty GND referencing as place holders and choose the best location for short
- Ensure the silkscreen indicates the test points with clear power rail and logic names. As well as the source for resistor calibration (refer to [Section 52.6](#), routing suggestions for current sense resistor calibration)

52.6 Routing Overview for Current Sense Resistor Calibration

Current sense resistor calibration can help test accuracy. Figures below provide a routing overview. The Sense+/- and Source+/- can be laid out to the test pins of Dupont header connectors

Figure 52-13.FIP Top/Bottom Side Current Sense Resistor Calibration - Routing Overview

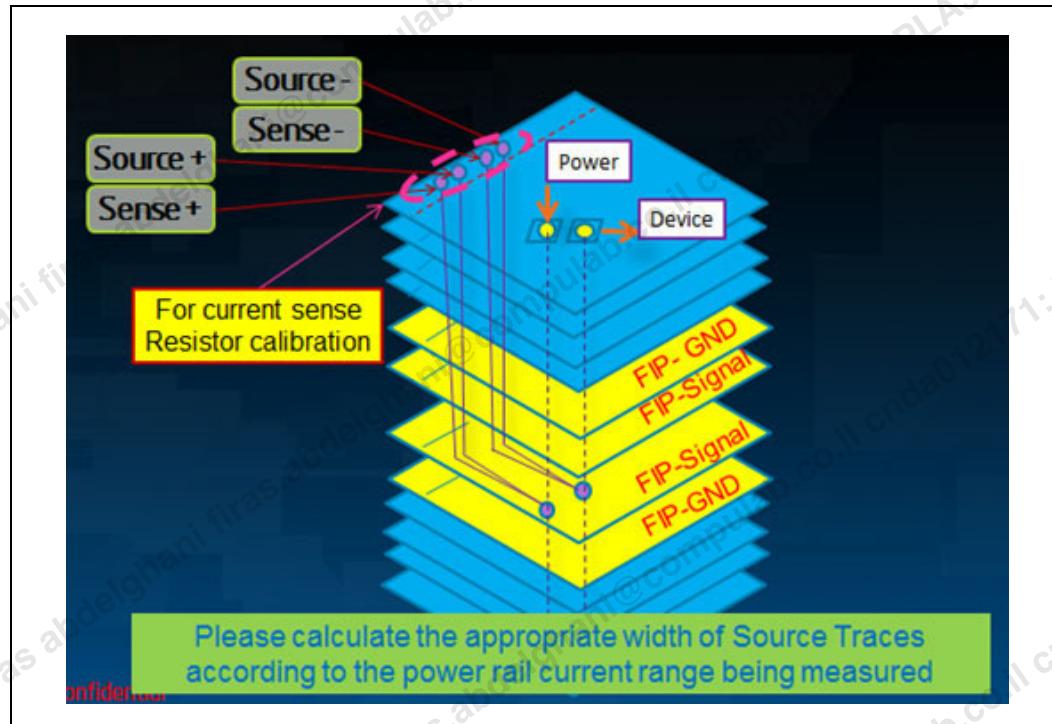
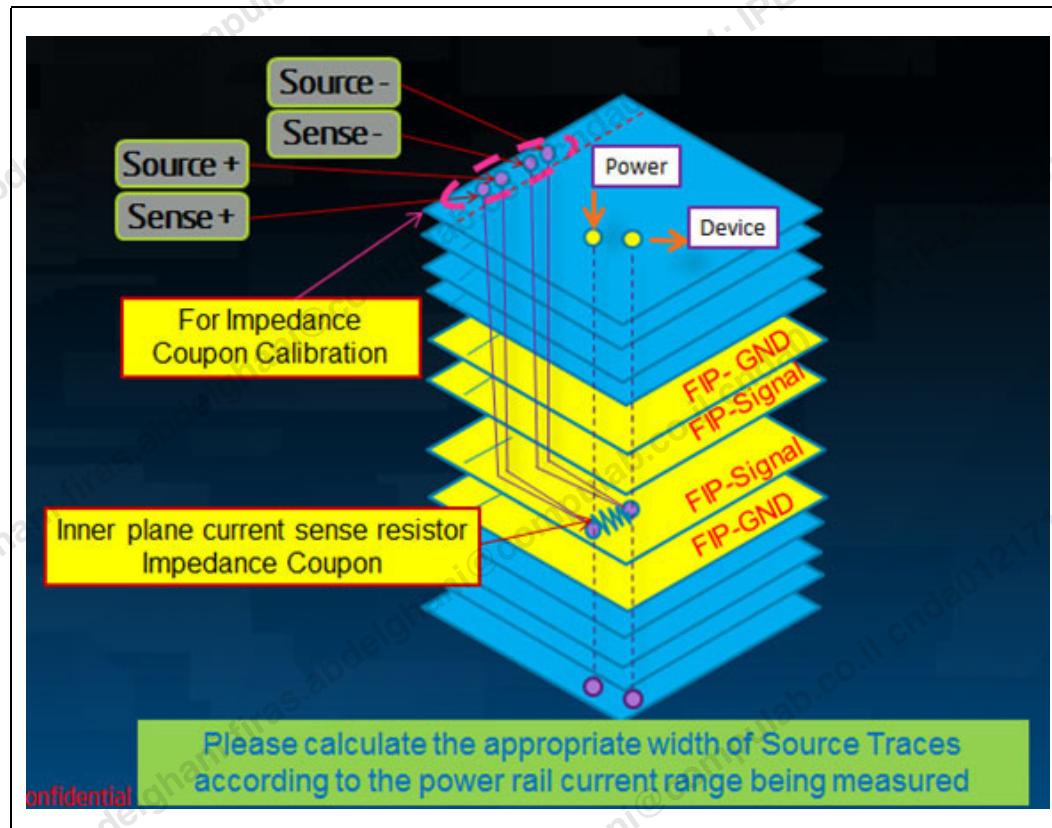


Figure 52-14.FIP Inner Layer Impedance Coupon Calibration - Routing Overview

52.7 General PCB Via/Trace Calculator Routing Guidelines

- <http://circuitcalculator.com/wordpress/2006/03/12/pcb-via-calculator/>
- <http://circuitcalculator.com/wordpress/2006/01/31/pcb-trace-width-calculator/>
- Other tools preferred by the ODMs/ OEMs

52.8 Summary

The FIP board could save up-to 3-7 days of effort when compared to manual instrumentation and setup for one test. The FIP layout solution will have minimum impact to layout engineers if it is planned at the beginning of the layout component placing and routing. One-layout-2-Gerber file method supports flexible FIP/Non-FIP PCB manufacturing and SMT assembly. It also saves cost and effort for Non-FIP as no extra layout effort or current sense resistors costs are needed at any product design stage.



53 Designing for Power Optimized S0ix Platforms (Connected Standby/Modern Standby)

53.1 Overview

Intel® S0 idle low power mode (S0ix) IA hardware features and Microsoft® Modern Standby operating system software features (MS, previously known as 'Connected Standby' or CS) work together as key power optimization capabilities that enable power efficient SoC platform designs.

The power efficient platform ecosystem (hardware, software, firmware) that integrates hardware S0ix and operating system Modern Standby power efficient architectures require that all independent hardware design features (SoC, PCIe, USB, SATA, GPIO, clocks, clock control, power delivery and control, PMIC, EC, VR, FETs, glue logic, level-shifters, repeaters, signal routing and termination, etc.) to be integrated accurately, completely and functionally robust according to all individual platform feature specifications listed in the Product Design Guide (PDG), External Design Specification (EDS), Firmware Architecture Specification/BIOS Writer's Guide (FAS/BWG respectively), Runtime D3 (RTD3) Guidelines, Device Power Recommendations Guide as well as industry specification requirements.

This is a critical design step to enabling S0 idle low power mode: BOM devices and software stack must support RTD3 requirements fully to enable the SoC power management architecture to enter the most power efficient states. Displays must support power efficient "Active" display states such as Panel Self-Refresh, or PSR to enable deep SoC core and package C-States. Devices and software stacks that do not have "clocks off" or "offloading" capability in addition to power efficient functionality will block SoC power efficient states and result with increased SoC and platform power consumption.

Any one or more features, components or devices that do not meet individual functional design specifications including device sleep and individual component or device power efficiency requirements block SoC, platform and OS deep sleep and have a negative impact on power and performance.

BOM and platform design choices also have a platform power efficiency where regulatory requirements are concerned including new California Energy Commission (CEC) regulatory requirements that are expected to impact all products manufactured on and after January 1, 2019. More information about new CEC regulatory requirement are available in the Coffee Lake Desktop / AIO S0 idle (S0ix) Design Recommendations Technical White Paper (RDC#571210). Regulatory resources outside the scope of this design reference must also be considered based on country and international regulatory requirements for products used in those specific regions.

S0ix power efficient design specification references are distributed throughout individual SoC Platform Design Guide (PDG) chapters and other hardware and software design guidance discussed above, therefore additional guidance will not be listed in this chapter to avoid duplication and associated synchronization issues. Refer to the specific



SoC PDG, EDS, RVP, industry feature specifications (PCIe, USB, SATA, etc.) and the key design references listed in the table below for the most up-to-date design specification and guidance to design for a power optimized S0ix SoC and platform ecosystem.

Additionally, S0 idle low power mode (S0ix) hardware designs require stable, fully functional legacy Sx design capabilities since BIOS FADT table can be disabled on S0ix platforms making the system default to an Sx only design. Sx flows must be fully functional and stable to support the additional power efficient capabilities available from RTD3 and S0ix platform design ecosystems.

In summary, final design power and performance capability is determined by board design, OS, drivers, power policies, BOM device and component capabilities choices. SoC and software stack can't workaround device and component lack of capability with the only resolution is to remove or replace devices and components that reduce or block low power efficiency. S0ix designs that integrate RTD3 capabilities continue to require support for Sx (S0, S3, S4, S5) design capabilities since legacy power sequence flows provide the design baseline for platform sleep states--even though S3 support and S0ix support are mutually exclusive capabilities: Either S3 is enabled and S0 idle low power mode (S0ix) is disabled, or S3 is disabled and S0ix is enabled.

53.1.1 S0 Idle (S0ix) SoC Design References

The low power S0 idle (S0ix) / Modern Standby ecosystem must consider many external design considerations beyond this hardware product design guide (PDG) since SoC connected devices, drivers, operating system, application software and firmware play significant roles to enable S0ix. The information will not be consolidated here to avoid duplication, missing detailed design requirements listed in the complete reference and to avoid out-of-sync confusion.

Refer to individual PDG feature sections and implement to specification. Designs must continue to meet Intel® Architecture (IA) platform design Sx requirements (Sleep States: S0, S3, S4, S5) since Sx functionality continues to provide the design capability base and power delivery flow controls for S0ix designs. Platform design choices are key factors that determine the final platform design capability that enable the design to meet power efficiency and regulatory targets.

For Coffee Lake, Microsoft* Windows 10 will be the only Windows client OS supported. As such, refer to Microsoft* Windows 10 MSDN for OS specific design recommendations that impact power management and power optimized performance.

California Energy Commission (CEC) has updated California regulatory requirements that intercept Coffee Lake product production time frame. Although the "Coffee Lake Desktop / AIO S0 idle (S0ix) Design Recommendations" White Paper (RDC#571210) is intended for CFL desktops and AIO designs, mobile hardware designers need to be aware of CEC regulatory impacts to overall CFL design implementation. Access the white paper and refer to section 4, entitled "2019 California Energy Commission (CEC) Computers impact" for details and direct references to CEC resources.

The following Key Design References for Power Optimization Designs below in the table are a partial list and is provided as a convenience. Work with your Intel Field AE and known power and performance AE team members and refine Intel collateral RDC, Validation Internet Portal (VIP), industry standards organizations, operating system manufacturer, endpoint device and component vendors for product specific feature design recommendation and requirements.

**Note:**

SoC signal “SLP_S0_B” (SLP_S0#) replaces the power control capability for S3 since S3 and S0ix (SLP_S0_B) power control are mutually exclusive. However, S3 must continue to be routed since software is capable to disable low power S0 idle (SLP_S0_B). This user setting is set at boot. Sx signals and states all continue to be required for S0ix platform designs. Refer to this product’s S0ix reference design (SDS or RVP) for guidance. Confirm that all SLP_* signals are routed according to PDG recommendations. Plan platform power maps for sufficient isolated device FET power control according to PDG and reference design recommendations and specific target design requirements.

Table 53-1. ¹Key Design References for Power Optimized Designs

Reference title	Reference Type: HW, SW, FW, etc.	Reference location, ID
System Energy Calculator for California Energy Commission (CEC) - Computer Regulation	Interactive CEC Calculator to confirm design decision feature impact on CEC Expandability Score (ES)	RDC#571644*
Cannon Lake Rest-of-Platform (ROP) Power Management Integrated Circuit (PMIC) for Premium Segment with Volume Segment Information (CFL leverages CNL SoC architecture)	Requirements Specification	RDC#560460*
Coffee Lake Runtime D3 Hardware and Software Recommendations	Design Guide	RDC#569310*
2017 Coffee Lake Platform Device Power Targets and Related Recommendations	Device Power Specification	RDC#571086*
2017 Coffee Lake Platform Firmware Architecture Specification	Firmware Architecture Specification (FAS)	RDC#570050*
Coffee Lake H DDR4 RVP Schematic	Schematic, Board, Symbol references	RDC#571483*
Coffee Lake S CRB Schematic		RDC#572913*
Coffee Lake S SODIMM RVP Schematic		RDC#573546*
Coffee Lake Desktop / AIO S0 idle (S0ix) Design Recommendations	S0ix design recommendations; California Energy Commission (CEC) regulatory resources	RDC#571210*
Battery Life: Debugging Power Problems with Standby	External to Intel - Microsoft Channel9 MSDN	https://channel9.msdn.com/Events/WinHEC/2015/OWD200 *
Modern Standby Design Decisions	External to Intel - Microsoft MSDN	MSDN page ID: "modern-standby-design-decisions" *
Modern Standby Power/Performance targets	External to Intel - Microsoft MSDN	MSDN page ID: "power-performance-targets" *
Modern Standby Tools available	External to Intel - Microsoft MSDN	MSDN page ID: "using-windows-performance-analyzer-to-analyze-modern-standby-issues" *
Powerhouse Mountain (PHM) - Intel Hardware Power optimization tool (available only with NDA)	Intel Software Tool: Power Optimization and Enabling	Validation Internet Portal (VIP): Product Documentation and Other software->Access Test software files. Accept terms of use. Search for "Mountain" then download and install the latest version. A PHM video walk-through may also be available in a separate VIP download.



Notes:

1. References and links confirmed as working on 5/25/2018

§ §



54 Compatibility with Other Platforms

54.1 Compatibility with Legacy Platforms

Coffee Lake H Processor is not forward or backward compatible with Kaby Lake H or Sky Lake H Processors.

There is a compatibility option between Coffee Lake H processor sku i.e., It is possible to mount CFL H 82 45W processor on CFL H 62 45W board and to mount CFL H 62 45W processor on CFL H 82 board. In order to implement this correctly the BIOS should be configured to the right processor capability. Refer to "CFL-H boards compatible and BIOS configuration Technical Advisory RDC#599797", "BIOS Writer Guide Rev 3.1.0 RDC#550049".

And also, it is possible to mount CFL H 82 45W processor on CFL H 62 65W RVP Board with minor reworks on RVP - Refer to "CFL H RVP User Guide RDC#572461". Please note that the proper BIOS configuration is required.

CNP PCH-H is not forward or backward compatible with KBP PCH-H or SPT PCH-H.

§ §